

EUROPEAN PATENT OFFICE
U.S. PATENT AND TRADEMARK OFFICE

CPC NOTICE OF CHANGES 1859

DATE: JANUARY 1, 2026

PROJECT RP12819

The following classification changes will be effected by this Notice of Changes:

<u>Action</u>	<u>Subclass</u>	<u>Group(s)</u>
SCHEME:		
Symbols Deleted:	H01L	21/48, 21/4803, 21/4807, 21/481, 21/4814, 21/4817, 21/4821, 21/4825, 21/4828, 21/4832, 21/4835, 21/4839, 21/4842, 21/4846, 21/485, 21/4853, 21/4857, 21/486, 21/4864, 21/4867, 21/4871, 21/4875, 21/4878, 21/4882, 21/4885, 21/4889, 21/4892, 21/4896, 21/50, 21/52, 21/54, 21/56, 21/561, 21/563, 21/565, 21/566, 21/568, 21/60, 2021/60007, 2021/60015, 2021/60022, 2021/6003, 2021/60037, 2021/60045, 2021/60052, 2021/6006, 2021/60067, 2021/60075, 2021/60082, 2021/6009, 2021/60097, 2021/60105, 2021/60112, 2021/6012, 2021/60127, 2021/60135, 2021/60142, 2021/6015, 2021/60157, 2021/60165, 2021/60172, 2021/6018, 2021/60187, 2021/60195, 2021/60202, 2021/6021, 2021/60217, 2021/60225, 2021/60232, 2021/6024, 2021/60247, 2021/60255, 2021/60262, 2021/6027, 2021/60277, 2021/60285, 2021/60292, 21/603, 21/607, 21/71, 21/74, 21/743, 21/746, 21/76, 21/7602, 21/7605, 21/7607, 21/761, 21/762, 21/76202, 21/76205, 21/76208, 21/7621, 21/76213, 21/76216, 21/76218, 21/76221, 21/76224, 21/76227, 21/76229, 21/76232, 21/76235, 21/76237, 21/76264, 21/76267, 21/7627, 21/76272, 21/76275, 21/76278, 21/76281, 21/76283, 21/76286, 21/76289, 21/76291, 21/76294, 21/76297, 21/763, 21/764, 21/765, 21/768, 21/76801, 21/76802, 21/76804, 21/76805, 21/76807, 21/76808, 21/7681, 21/76811, 21/76813, 21/76814, 21/76816, 21/76817, 21/76819, 21/7682, 21/76822, 21/76823, 21/76825, 21/76826, 21/76828, 21/76829, 21/76831, 21/76832, 21/76834, 21/76835, 21/76837, 21/76838, 21/7684, 21/76841, 21/76843, 21/76844, 21/76846, 21/76847, 21/76849, 21/7685, 21/76852, 21/76853, 21/76855, 21/76856, 21/76858, 21/76859, 21/76861, 21/76862, 21/76864, 21/76865, 21/76867, 21/76868, 21/7687, 21/76871, 21/76873, 21/76874, 21/76876, 21/76877, 21/76879, 21/7688, 21/76882, 21/76883, 21/76885, 21/76886, 21/76888, 21/76889, 21/76891, 21/76892, 21/76894, 21/76895, 21/76897, 21/76898

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	H01L	23/00, 23/02, 23/04, 23/041, 23/043, 23/045, 23/047, 23/049, 23/051, 23/053, 23/055, 23/057, 23/06, 23/08, 23/10, 23/12, 23/13, 23/14, 23/142, 23/145, 23/147, 23/15, 23/16, 23/18, 23/20, 23/22, 23/24, 23/26, 23/28, 23/29, 23/291, 23/293, 23/295, 23/296, 23/298, 23/31, 23/3107, 23/3114, 23/3121, 23/3128, 23/3135, 23/3142, 23/315, 23/3157, 23/3164, 23/3171, 23/3178, 23/3185, 23/3192, 23/32, 23/34, 23/345, 23/36, 23/367, 23/3672, 23/3675, 23/3677, 23/373, 23/3731, 23/3732, 23/3733, 23/3735, 23/3736, 23/3737, 23/3738, 23/38, 23/40, 23/4006, 23/4012, 2023/4018, 2023/4025, 2023/4031, 2023/4037, 2023/4043, 2023/405, 2023/4056, 2023/4062, 2023/4068, 2023/4075, 2023/4081, 2023/4087, 23/4093, 23/42, 23/427, 23/4275, 23/433, 23/4332, 23/4334, 23/4336, 23/4338, 23/44, 23/445, 23/46, 23/467, 23/473, 23/4735, 23/48, 23/481, 23/482, 23/4821, 23/4822, 23/4824, 23/4825, 23/4827, 23/4828, 23/485, 23/4855, 23/488, 23/49, 23/492, 23/4922, 23/4924, 23/4926, 23/4928, 23/495, 23/49503, 23/49506, 23/4951, 23/49513, 23/49517, 23/4952, 23/49524, 23/49527, 23/49531, 23/49534, 23/49537, 23/49541, 23/49544, 23/49548, 23/49551, 23/49555, 23/49558, 23/49562, 23/49565, 23/49568, 23/49572, 23/49575, 23/49579, 23/49582, 23/49586, 23/49589, 23/49593, 23/49596, 23/498, 23/49805, 23/49811, 23/49816, 23/49822, 23/49827, 23/49833, 23/49838, 23/49844, 23/4985, 23/49855, 23/49861, 23/49866, 23/49872, 23/49877, 23/49883, 23/49888, 23/49894, 23/50, 23/52, 23/522, 23/5221, 23/5222, 23/5223, 23/5225, 23/5226, 23/5227, 23/5228, 23/525, 23/5252, 23/5254, 23/5256, 23/5258, 23/528, 23/5283, 23/5286, 23/532, 23/53204, 23/53209, 23/53214, 23/53219, 23/53223, 23/53228, 23/53233, 23/53238, 23/53242, 23/53247, 23/53252, 23/53257, 23/53261, 23/53266, 23/53271, 23/53276, 23/5328, 23/53285, 23/5329, 23/53295, 23/535, 23/538, 23/5381, 23/5382, 23/5383, 23/5384, 23/5385, 23/5386, 23/5387, 23/5388, 23/5389, 23/544, 23/552, 23/556, 23/562, 23/564, 23/57, 23/573, 23/576, 23/58, 23/585, 23/60, 23/62, 23/64, 23/642, 23/645, 23/647, 23/66

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	H01L	24/00, 24/01, 24/02, 24/03, 24/04, 24/05, 24/06, 24/07, 24/08, 24/09, 24/10, 24/11, 24/12, 24/13, 24/14, 24/15, 24/16, 24/17, 24/18, 24/19, 24/20, 24/23, 24/24, 24/25, 24/26, 24/27, 24/28, 24/29, 24/30, 24/31, 24/32, 24/33, 24/34, 24/35, 24/36, 24/37, 24/38, 24/39, 24/40, 24/41, 24/42, 24/43, 24/44, 24/45, 24/46, 24/47, 24/48, 24/49, 24/50, 24/63, 24/64, 24/65, 24/66, 24/67, 24/68, 24/69, 24/70, 24/71, 24/72, 24/73, 24/74, 24/741, 24/742, 24/743, 24/744, 24/745, 24/75, 24/76, 24/77, 24/78, 24/79, 24/799, 24/80, 24/81, 24/82, 24/83, 24/84, 24/85, 24/86, 24/89, 24/90, 24/91, 24/92, 24/93, 24/94, 24/95, 24/96, 24/97, 24/98
	H01L	25/00, 25/03, 25/04, 25/041, 25/042, 25/043, 25/065, 25/0652, 25/0655, 25/0657, 25/07, 25/071, 25/072, 25/073, 25/074, 25/075, 25/0753, 25/0756, 25/10, 25/105, 25/11, 25/112, 25/115, 25/117, 25/13, 25/16, 25/162, 25/165, 25/167, 25/18, 25/50
	H01L	2221/10, 2221/1005, 2221/101, 2221/1015, 2221/1021, 2221/1026, 2221/1031, 2221/1036, 2221/1042, 2221/1047, 2221/1052, 2221/1057, 2221/1063, 2221/1068, 2221/1073, 2221/1078, 2221/1084, 2221/1089, 2221/1094
	H01L	2223/00, 2223/544, 2223/54406, 2223/54413, 2223/5442, 2223/54426, 2223/54433, 2223/5444, 2223/54446, 2223/54453, 2223/5446, 2223/54466, 2223/54473, 2223/5448, 2223/54486, 2223/54493, 2223/58, 2223/64, 2223/66, 2223/6605, 2223/6611, 2223/6616, 2223/6622, 2223/6627, 2223/6633, 2223/6638, 2223/6644, 2223/665, 2223/6655, 2223/6661, 2223/6666, 2223/6672, 2223/6677, 2223/6683, 2223/6688, 2223/6694

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Symbols New:	H10W	SUBCLASS
	H10W	10/00, 10/01, 10/011, 10/012, 10/0121, 10/0123, 10/0124, 10/0125, 10/0126, 10/0127, 10/0128, 10/014, 10/0142, 10/0143, 10/0145, 10/0147, 10/0148, 10/018, 10/019, 10/021, 10/031, 10/041, 10/051, 10/061, 10/10, 10/13, 10/17, 10/181, 10/20, 10/30, 10/40, 10/50
	H10W	15/00, 15/01

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	H10W	20/00, 20/01, 20/021, 20/023, 20/0234, 20/0238, 20/0242, 20/0245, 20/0249, 20/0253, 20/0257, 20/0261, 20/0265, 20/031, 20/032, 20/033, 20/034, 20/035, 20/036, 20/037, 20/0372, 20/0375, 20/038, 20/039, 20/041, 20/042, 20/0425, 20/043, 20/044, 20/045, 20/046, 20/047, 20/048, 20/049, 20/051, 20/052, 20/0523, 20/0526, 20/054, 20/055, 20/0552, 20/0554, 20/056, 20/057, 20/058, 20/059, 20/0595, 20/062, 20/063, 20/0633, 20/0636, 20/064, 20/065, 20/066, 20/067, 20/068, 20/069, 20/0693, 20/0696, 20/0698, 20/071, 20/072, 20/074, 20/075, 20/076, 20/0765, 20/077, 20/081, 20/082, 20/083, 20/084, 20/085, 20/086, 20/087, 20/088, 20/0882, 20/0884, 20/0886, 20/0888, 20/089, 20/091, 20/092, 20/093, 20/094, 20/095, 20/096, 20/097, 20/098, 20/20, 20/211, 20/212, 20/2125, 20/2128, 20/213, 20/2134, 20/215, 20/216, 20/217, 20/218, 20/222, 20/233, 20/40, 20/41, 20/42, 20/421, 20/422, 20/423, 20/425, 20/427, 20/43, 20/432, 20/435, 20/438, 20/44, 20/4403, 20/4405, 20/4407, 20/4421, 20/4424, 20/4432, 20/4435, 20/4437, 20/4441, 20/4446, 20/4451, 20/4462, 20/4473, 20/4484, 20/45, 20/455, 20/46, 20/47, 20/48, 20/481, 20/482, 20/483, 20/484, 20/49, 20/491, 20/492, 20/493, 20/494, 20/495, 20/496, 20/497, 20/498
	H10W	29/00, 29/01
	H10W	40/00, 40/01, 40/03, 40/033, 40/037, 40/10, 40/20, 40/22, 40/226, 40/228, 40/231, 40/233, 40/235, 40/237, 40/242, 40/25, 40/251, 40/253, 40/254, 40/255, 40/257, 40/258, 40/259, 40/28, 40/30, 40/305, 40/40, 40/43, 40/47, 40/475, 40/50, 40/60, 40/611, 40/613, 40/625, 40/641, 40/70, 40/73, 40/735, 40/77, 40/772, 40/774, 40/776, 40/778, 40/80
	H10W	42/00, 42/101, 42/121, 42/20, 42/25, 42/261, 42/263, 42/265, 42/267, 42/271, 42/273, 42/276, 42/281, 42/284, 42/287, 42/40, 42/405, 42/60, 42/80
	H10W	44/00, 44/20, 44/203, 44/206, 44/209, 44/212, 44/216, 44/219, 44/223, 44/226, 44/231, 44/234, 44/241, 44/243, 44/248, 44/251, 44/255, 44/259, 44/401, 44/501, 44/601
	H10W	46/00, 46/101, 46/103, 46/106, 46/201, 46/301, 46/401, 46/403, 46/407, 46/501, 46/503, 46/507, 46/601, 46/603, 46/607

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	H10W	70/00, 70/01, 70/02, 70/023, 70/027, 70/04, 70/041, 70/042, 70/045, 70/047, 70/048, 70/05, 70/06, 70/08, 70/09, 70/092, 70/093, 70/095, 70/096, 70/097, 70/098, 70/099, 70/20, 70/22, 70/24, 70/26, 70/28, 70/40, 70/411, 70/413, 70/415, 70/417, 70/421, 70/424, 70/427, 70/429, 70/433, 70/435, 70/438, 70/442, 70/451, 70/453, 70/456, 70/457, 70/458, 70/461, 70/464, 70/465, 70/466, 70/467, 70/468, 70/474, 70/475, 70/476, 70/479, 70/481, 70/60, 70/611, 70/614, 70/616, 70/618, 70/62, 70/63, 70/635, 70/641, 70/644, 70/65, 70/652, 70/6523, 70/6525, 70/6528, 70/654, 70/655, 70/656, 70/6565, 70/657, 70/658, 70/66, 70/662, 70/664, 70/666, 70/668, 70/67, 70/68, 70/681, 70/682, 70/685, 70/686, 70/687, 70/6875, 70/688, 70/69, 70/692, 70/695, 70/698, 70/699

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	H10W	74/00, 74/01, 74/012, 74/014, 74/016, 74/017, 74/019, 74/10, 74/111, 74/114, 74/117, 74/121, 74/124, 74/127, 74/129, 74/131, 74/134, 74/137, 74/141, 74/142, 74/144, 74/147, 74/15, 74/40, 74/43, 74/47, 74/473, 74/476, 74/481
	H10W	76/00, 76/01, 76/05, 76/10, 76/12, 76/13, 76/132, 76/134, 76/136, 76/138, 76/15, 76/153, 76/157, 76/161, 76/165, 76/167, 76/17, 76/18, 76/40, 76/42, 76/43, 76/45, 76/47, 76/48, 76/60, 76/63, 76/67
	H10W	78/00
	H10W	80/00, 80/011, 80/016, 80/023, 80/031, 80/033, 80/035, 80/037, 80/041, 80/102, 80/161, 80/163, 80/165, 80/168, 80/211, 80/301, 80/312, 80/314, 80/327, 80/331, 80/333, 80/334, 80/335, 80/337, 80/338, 80/339, 80/341, 80/701, 80/721, 80/732, 80/743, 80/754
	H10W	90/00, 90/10, 90/15, 90/155, 90/20, 90/22, 90/231, 90/24, 90/26, 90/271, 90/275, 90/28, 90/284, 90/288, 90/291, 90/293, 90/295, 90/297, 90/401, 90/701, 90/721, 90/722, 90/723, 90/724, 90/725, 90/726, 90/727, 90/728, 90/729, 90/7295, 90/731, 90/732, 90/733, 90/734, 90/735, 90/736, 90/737, 90/738, 90/739, 90/751, 90/752, 90/753, 90/754, 90/755, 90/756, 90/757, 90/758, 90/759, 90/761, 90/762, 90/763, 90/764, 90/765, 90/766, 90/767, 90/768, 90/769, 90/791, 90/792, 90/794, 90/796, 90/798, 90/811
	H10W	95/00
	H10W	99/00
Warnings Deleted:	H01L	25/04, 25/065, 25/0652, 25/0655, 25/0657, 25/16, 25/162, 25/165, 25/167, 25/18
Warnings New:	H10D	80/00
	H10F	39/90

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<u>Action</u>	<u>Subclass</u>	<u>Group(s)</u>
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	H10W	20/023, 20/0234, 20/037, 20/0372, 20/056, 20/0595, 20/063, 20/0633, 20/069, 20/0693, 20/20, 20/211, 20/212, 20/213, 20/216, 20/222, 20/233, 20/40, 20/41, 20/42, 20/421, 20/422, 20/425, 20/4403, 20/4437, 20/45, 20/455, 20/481, 20/482
	H10W	40/00, 40/01, 40/03, 40/033, 40/20, 40/22, 40/226, 40/231, 40/50, 40/80,
	H10W	42/00, 42/101, 42/20, 42/261, 42/281, 42/40
	H10W	70/00, 70/02, 70/027, 70/05, 70/06, 70/08, 70/092, 70/60, 70/611, 70/618, 70/62, 70/65, 70/652, 70/654, 70/6565, 70/657, 70/66, 70/662, 70/67, 70/685, 70/686, 70/687, 70/688, 70/69, 70/692, 70/699
	H10W	72/00, 72/01, 72/011, 72/012, 72/01204, 72/01221, 72/01231, 72/01251, 72/01261, 72/013, 72/01304, 72/01321, 72/01331, 72/01351, 72/01361, 72/014, 72/015, 72/01504, 72/016, 72/01604, 72/019, 72/01904, 72/01921, 72/01931, 72/01951, 72/01961, 72/0198, 72/07204, 72/07207, 72/07232, 72/07233, 72/07236, 72/07332, 72/07333, 72/07336, 72/074, 72/07532, 72/07533, 72/07536, 72/07632, 72/07633, 72/07636, 72/20, 72/221, 72/231, 72/241, 72/251, 72/261, 72/281, 72/30, 72/321, 72/331, 72/341, 72/351, 72/361, 72/381, 72/40, 72/50, 72/521, 72/531, 72/541, 72/551, 72/581, 72/60, 72/621, 72/631, 72/641, 72/651, 72/681, 72/691, 72/701, 72/801, 72/812, 72/823, 72/90, 72/921, 72/931, 72/941, 72/951, 72/961, 72/981
	H10W	74/01, 74/10, 74/15
	H10W	76/01, 76/132, 76/60, 76/63
	H10W	90/00, 90/10, 90/20, 90/701, 90/721, 90/724, 90/725, 90/726, 90/7295, 90/731, 90/751, 90/754, 90/755, 90/756, 90/761, 90/764, 90/765, 90/791, 90/811
	H10W	95/00
	H10W	99/00
Warnings Modified:	H10B	80/00
	H10H	29/30
Notes Deleted:	H01L	21/48, 21/50, 21/768, 21/76838
	H01L	23/00, 23/18, 23/48, 23/544, 23/66
	H01L	24/00
	H01L	25/00, 25/065, 25/07, 25/105, 25/11
	H01L	2924/0001
Notes New:	H10W	SUBCLASS
	H10W	20/00
	H10W	46/00
	H10W	72/00
	H10W	76/42
	H10W	80/00

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<u>Action</u>	<u>Subclass</u>	<u>Group(s)</u>
	H10W	90/00
Notes Modified:	H10D	SUBCLASS
Guidance Headings New:	H10W	10/00
	H10W	40/00
	H10W	70/00
DEFINITIONS:		
Definitions Deleted: (no frozen (F) symbol definitions should be deleted)	H01L	21/48, 21/50, 21/71, 21/74, 21/743, 21/76, 21/762, 21/76224, 21/768, 21/76804, 21/76805, 21/76808, 21/7681, 21/76811, 21/76813, 21/76814, 21/76816, 21/76817, 21/76819, 21/76822, 21/76823, 21/76825, 21/76826, 21/76828, 21/76829, 21/76831, 21/76832, 21/76834, 21/76835, 21/76837, 21/76838, 21/76843, 21/76844, 21/76846, 21/76847, 21/76849, 21/7685, 21/76852, 21/76853, 21/76855, 21/76856, 21/76858, 21/76859, 21/76861, 21/76862, 21/76864, 21/76865, 21/76867, 21/76868, 21/7687, 21/76871, 21/76874, 21/76879, 21/7688, 21/76883, 21/76885, 21/76886, 21/76897, 21/76898
	H01L	23/00, 23/02, 23/055, 23/12, 23/147, 23/16, 23/20, 23/22, 23/24, 23/28, 23/295, 23/3157, 23/3178, 23/32, 23/34, 23/36, 23/367, 23/3672, 23/3731, 23/3732, 23/3733, 23/3736, 23/4012, 23/42, 23/427, 23/4334, 23/44, 23/46, 23/467, 23/473, 23/4735, 23/48, 23/482, 23/485, 23/488, 23/495, 23/49506, 23/49544, 23/49548, 23/49572, 23/498, 23/49811, 23/49822, 23/49827, 23/4985, 23/49855, 23/49861, 23/49866, 23/49877, 23/49883, 23/50, 23/5222, 23/5227, 23/5228, 23/528, 23/53209, 23/53276, 23/535, 23/538, 23/5383, 23/5384, 23/5387, 23/5388, 23/544, 23/552, 23/58, 23/585, 23/60, 23/642, 23/645, 23/647
	H01L	24/00, 24/02, 24/06, 24/10, 24/11, 24/12, 24/14, 24/18, 24/26, 24/27, 24/34, 24/50, 24/71, 24/80, 24/82, 24/85, 24/93, 24/96
	H01L	25/00, 25/03, 25/042, 25/043, 25/075, 25/16, 25/18, 25/50
	H01L	2223/6644, 2223/6661, 2223/6672, 2223/6677

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<u>Action</u>	<u>Subclass</u>	<u>Group(s)</u>
	H01L	2224/03422, 2224/03424, 2224/036, 2224/0383, 2224/05187, 2224/05287, 2224/05387, 2224/05487, 2224/05687, 2224/05787, 2224/05887, 2224/05987, 2224/0912, 2224/11422, 2224/11424, 2224/116, 2224/1183, 2224/13187, 2224/13287, 2224/13387, 2224/13487, 2224/13687, 2224/13787, 2224/13887, 2224/13987, 2224/1712, 2224/27422, 2224/27424, 2224/276, 2224/2783, 2224/29021, 2224/29187, 2224/29287, 2224/29387, 2224/29487, 2224/29687, 2224/29787, 2224/29887, 2224/29987, 2224/3312, 2224/37187, 2224/37287, 2224/37387, 2224/37487, 2224/37687, 2224/37787, 2224/37887, 2224/37987, 2224/45187, 2224/45287, 2224/45387, 2224/45487, 2224/45687, 2224/45787, 2224/45887, 2224/45987, 2224/48687, 2224/48787, 2224/48887, 2224/80052, 2224/80237, 2224/80379, 2224/80487, 2224/80587, 2224/80687, 2224/80787, 2224/80901, 2224/81052, 2224/81237, 2224/81379, 2224/81487, 2224/81587, 2224/81687, 2224/81787, 2224/81901, 2224/82237, 2224/83052, 2224/83237, 2224/83379, 2224/83487, 2224/83587, 2224/83687, 2224/83787, 2224/84237, 2224/84487, 2224/84587, 2224/84687, 2224/84787, 2224/85237, 2224/85487, 2224/85587, 2224/85687, 2224/85787, 2224/86237
	H01L	2225/06541, 2225/06593, 2225/06596, 2225/107
	H01L	2924/06, 2924/16174

The following subclasses/groups are also impacted by this Notice of Changes (indicate subclasses/groups outside of the project scope, such as those listed in the CRL):

B81C, G01R, H05K, C04B, G02B, G01J, F25D, H01H, G03F, G01T, A41D, B21C, B21J, B29C, B81B, C03C, C08G, C08L, C09G, C09J, F21K, F21V, F24F, F25D, F28D, F28F, G01K, G02F, G06K, G06Q, G06V, G09F, G11B, G11C, G12B, H01F, H01J, H01P, H01Q, H01S, H02H, H02K, H03F, H05F, H10B, H10D, H10F, H10H, H10N

This Notice of Changes includes the following [Check the ones included]:

1. CLASSIFICATION SCHEME CHANGES

- ☒ A. New, Modified or Deleted Group(s)
- ☒ B. New, Modified or Deleted Warning(s)
- ☒ C. New, Modified or Deleted Note(s)
- ☒ D. New, Modified or Deleted Guidance Heading(s)

2. DEFINITIONS

- ☐ A. New or Modified Definitions (Full definition template)
- ☒ B. Modified or Deleted Definitions (Definitions Quick Fix)

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- 3. ☒ REVISION CONCORDANCE LIST (RCL)
- 4. ☒ CHANGES TO THE CPC-TO-IPC CONCORDANCE LIST (CICL)
- 5. ☒ CHANGES TO THE CROSS-REFERENCE LIST (CRL)

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1. CLASSIFICATION SCHEME CHANGES

A. New, Modified or Deleted Group(s)

SUBCLASS H01L - SEMICONDUCTOR DEVICES NOT COVERED BY CLASS H10

<u>Type*</u>	<u>Symbol</u>	<u>Indent Level Number of dots (e.g. 0, 1, 2)</u>	<u>Title</u> <u>“CPC only” text should normally be enclosed in {curly brackets}**</u>	<u>Transferred to#</u>
D	H01L21/48	3	Manufacture or treatment of parts, e.g. containers, prior to assembly of the devices, using processes not provided for in a single one of the groups H01L21/18 - H01L21/326 or H10D48/04 - H10D48/07	<administrative transfer to H10W 99/00>
D	H01L21/4803	4	{Insulating or insulated parts, e.g. mountings, containers, diamond heatsinks (H01L21/4846 takes precedence; printed circuit boards H05K1/00)}	<administrative transfer to H10W 99/00>
D	H01L21/4807	5	{Ceramic parts}	<administrative transfer to H10W 99/00>
D	H01L21/481	5	{Insulating layers on insulating parts, with or without metallisation}	<administrative transfer to H10W 99/00>
D	H01L21/4814	4	{Conductive parts}	<administrative transfer to H10W 99/00>
D	H01L21/4817	5	{for containers, e.g. caps (H01L21/4871 takes precedence)}	<administrative transfer to H10W 76/01>
D	H01L21/4821	5	{Flat leads, e.g. lead frames with or without insulating supports}	<administrative transfer to H10W 70/04>
D	H01L21/4825	6	{Connection or disconnection of other leads to or from flat leads, e.g. wires, bumps, other flat leads}	<administrative transfer to H10W 70/041>
D	H01L21/4828	6	{Etching (etching for cleaning without patterning H01L21/4835)}	<administrative transfer to H10W 70/042>
D	H01L21/4832	7	{Etching a temporary substrate after encapsulation process to form leads}	<administrative transfer to H10W 70/042>
D	H01L21/4835	6	{Cleaning, e.g. removing of solder}	<administrative transfer to H10W 70/045>
D	H01L21/4839	6	{Assembly of a flat lead with an insulating support, e.g. for TAB}	<administrative transfer to H10W 70/047>

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D	H01L21/4842	6	{Mechanical treatment, e.g. punching, cutting, deforming, cold welding}	<administrative transfer to H10W 70/048>
D	H01L21/4846	5	{Leads on or in insulating or insulated substrates, e.g. metallisation (H01L21/4821 takes precedence; metallisation of ceramics in general C04B41/51; printed circuits H05K3/00)}	<administrative transfer to H10W 70/05>
D	H01L21/485	6	{Adaptation of interconnections, e.g. engineering charges, repair techniques}	<administrative transfer to H10W 70/092>
D	H01L21/4853	6	{Connection or disconnection of other leads to or from a metallisation, e.g. pins, wires, bumps}	<administrative transfer to H10W 70/093>
D	H01L21/4857	6	{Multilayer substrates (multilayer metallisation on monolayer substrate H01L21/4846)}	<administrative transfer to H10W 70/05>
D	H01L21/486	6	{Via connections through the substrate with or without pins}	<administrative transfer to H10W 70/095>
D	H01L21/4864	6	{Cleaning, e.g. removing of solder}	<administrative transfer to H10W 70/097>
D	H01L21/4867	6	{Applying pastes or inks, e.g. screen printing (H01L21/486 takes precedence)}	<administrative transfer to H10W 70/098>
D	H01L21/4871	5	{Bases, plates or heatsinks}	<administrative transfer to H10W 70/02>
D	H01L21/4875	6	{Connection or disconnection of other leads to or from bases or plates}	<administrative transfer to H10W 70/023>
D	H01L21/4878	6	{Mechanical treatment, e.g. deforming}	<administrative transfer to H10W 70/027>
D	H01L21/4882	6	{Assembly of heatsink parts}	<administrative transfer to H10W 40/037>
D	H01L21/4885	5	{Wire-like parts or pins (wire ball formation B23K20/00; methods related to connecting semiconductor or other solid state bodies H01L24/00)}	<administrative transfer to H10W 72/50>
D	H01L21/4889	6	{Connection or disconnection of other leads to or from wire-like parts, e.g. wires}	<administrative transfer to H10W 72/075>
D	H01L21/4892	6	{Cleaning}	<administrative transfer to H10W 72/01571>
D	H01L21/4896	6	{Mechanical treatment, e.g. cutting, bending}	<administrative transfer to H10W 72/015>

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D	H01L21/50	3	Assembly of semiconductor devices using processes or apparatus not provided for in a single one of the groups H01L 21/18 - H01L 21/326 or H10D 48/04 - H10D 48/07 {e.g. sealing of a cap to a base of a container}	<administrative transfer to H10W 95/00>
D	H01L21/52	4	Mounting semiconductor bodies in containers	<administrative transfer to H10W 72/071>
D	H01L21/54	4	Providing fillings in containers, e.g. gas fillings	<administrative transfer to H10W 76/05>
D	H01L21/56	4	Encapsulations, e.g. encapsulation layers, coatings	<administrative transfer to H10W 74/01>
D	H01L21/561	5	{Batch processing}	<administrative transfer to H10W 74/014>
D	H01L21/563	5	{Encapsulation of active face of flip-chip device, e.g. underfilling or underencapsulation of flip-chip, encapsulation preform on chip or mounting substrate}	<administrative transfer to H10W 74/012 and H10W 74/15 simultaneously>
D	H01L21/565	5	{Moulds}	<administrative transfer to H10W 74/016>
D	H01L21/566	6	{Release layers for moulds, e.g. release layers, layers against residue during moulding}	<administrative transfer to H10W 74/017>
D	H01L21/568	5	{Temporary substrate used as encapsulation process aid (H01L 21/4832 and H01L 21/566 take precedence)}	<administrative transfer to H10W 74/019>
D	H01L21/60	4	Attaching {or detaching} leads or other conductive members, to be used for carrying current to or from the device in operation	<administrative transfer to H10W 72/071>
D	H01L2021/60007	5	{involving a soldering or an alloying process}	<administrative transfer to H10W 72/07236>
D	H01L2021/60015	6	{using plate connectors, e.g. layer, film}	<administrative transfer to H10W 72/20>

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D	H01L2021/60022	6	{using bump connectors, e.g. for flip chip mounting}	<administrative transfer to H10W 72/072>
D	H01L2021/6003	7	{Apparatus therefor}	<administrative transfer to H10W 72/0711>
D	H01L2021/60037	7	{Right-up bonding}	<administrative transfer to H10W 72/07261>
D	H01L2021/60045	7	{Pre-treatment step of the bump connectors prior to bonding}	<administrative transfer to H10W 72/07211>
D	H01L2021/60052	8	{Oxide removing step, e.g. flux, rosin}	<administrative transfer to H10W 72/07211 and H10W 72/01271 simultaneously>
D	H01L2021/6006	7	{with temporary supporting member not part of an apparatus, e.g. removable coating, film or substrate}	<administrative transfer to H10W 72/07204>
D	H01L2021/60067	7	{Aligning the bump connectors with the mounting substrate}	<administrative transfer to H10W 72/07221>
D	H01L2021/60075	8	{involving active alignment, i.e. by apparatus steering, e.g. using alignment marks, sensors}	<administrative transfer to H10W 72/07223>
D	H01L2021/60082	8	{involving passive alignment, e.g. using surface energy, chemical reactions, thermal equilibrium}	<administrative transfer to H10W 72/07221>
D	H01L2021/6009	8	{involving guiding structures, e.g. structures that are left at least partly in the bonded product, spacers}	<administrative transfer to H10W 72/07227>
D	H01L2021/60097	7	{Applying energy, e.g. for the soldering or alloying process}	<administrative transfer to H10W 72/07231>
D	H01L2021/60105	8	{using electromagnetic radiation}	<administrative transfer to H10W 72/07235>
D	H01L2021/60112	9	{Coherent radiation, i.e. laser beam}	<administrative transfer to H10W 72/07235>
D	H01L2021/6012	9	{Incoherent radiation, e.g. polychromatic heating lamp}	<administrative transfer to H10W 72/07235>
D	H01L2021/60127	9	{Induction heating, i.e. eddy currents}	<administrative transfer to H10W 72/07235>

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D	H01L2021/60135	8	{using convection, e.g. reflow oven}	<administrative transfer to H10W 72/07234>
D	H01L2021/60142	9	{with a graded temperature profile}	<administrative transfer to H10W 72/07234>
D	H01L2021/6015	8	{using conduction, e.g. chuck heater, thermocompression}	<administrative transfer to H10W 72/07232>
D	H01L2021/60157	9	{with a graded temperature profile}	<administrative transfer to H10W 72/07232>
D	H01L2021/60165	8	{using an electron beam}	<administrative transfer to H10W 72/07231>
D	H01L2021/60172	8	{using static pressure}	<administrative transfer to H10W 72/07231>
D	H01L2021/6018	9	{Unidirectional static pressure}	<administrative transfer to H10W 72/07231>
D	H01L2021/60187	9	{Isostatic pressure, e.g. degassing using vacuum or pressurised liquid}	<administrative transfer to H10W 72/07231>
D	H01L2021/60195	8	{using dynamic pressure, e.g. ultrasonic or thermosonic bonding}	<administrative transfer to H10W 72/07231>
D	H01L2021/60202	8	{using a protective atmosphere, e.g. with forming or shielding gas}	<administrative transfer to H10W 72/07241>
D	H01L2021/6021	8	{using an autocatalytic reaction}	<administrative transfer to H10W 72/07231>
D	H01L2021/60217	7	{Detaching bump connectors, e.g. after testing}	<administrative transfer to H10W 72/072>
D	H01L2021/60225	7	{Arrangement of bump connectors prior to mounting}	<administrative transfer to H10W 72/072 and H10W 72/247 simultaneously>
D	H01L2021/60232	8	{wherein the bump connectors are disposed only on the semiconductor chip}	<administrative transfer to H10W 72/072 and H10W 72/247 simultaneously>

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D	H01L2021/6024	8	{wherein the bump connectors are disposed only on the mounting substrate}	<administrative transfer to H10W 72/072 and H10W 72/247 simultaneously>
D	H01L2021/60247	8	{wherein the bump connectors are disposed on both the semiconductor chip and the mounting substrate, e.g. bump to bump}	<administrative transfer to H10W 72/072 and H10W 72/247 simultaneously>
D	H01L2021/60255	8	{wherein the bump connectors are provided as prepeg, e.g. are provided in an insulating plate member}	<administrative transfer to H10W 72/01212>
D	H01L2021/60262	8	{Lateral distribution of bump connectors prior to mounting}	<administrative transfer to H10W 72/072 and H10W 72/247 simultaneously>
D	H01L2021/6027	6	{Mounting on semiconductor conductive members}	<administrative transfer to H10W 72/07236>
D	H01L2021/60277	5	{involving the use of conductive adhesives}	<administrative transfer to H10W 72/30>
D	H01L2021/60285	5	{involving the use of mechanical auxiliary parts without the use of an alloying or soldering process, e.g. pressure contacts}	<administrative transfer to H10W 72/071>
D	H01L2021/60292	5	{involving the use of an electron or laser beam}	<administrative transfer to H10W 72/071>
D	H01L21/603	5	involving the application of pressure, e.g. thermo-compression bonding (H01L21/607 takes precedence)	<administrative transfer to H10W 72/07232>
D	H01L21/607	5	involving the application of mechanical vibrations, e.g. ultrasonic vibrations	<administrative transfer to H10W 72/07233>
D	H01L21/71	2	Manufacture of specific parts of devices defined in group H01L 21/70 ({H01L 21/0405, H01L 21/0445}, H01L 21/28, H01L 21/44, H01L 21/48 take precedence)	<administrative transfer to H10W 29/00 and H10W 29/01 simultaneously>

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D	H01L21/74	3	Making of {localized} buried regions, e.g. buried collector layers, internal connections {substrate contacts}	<administrative transfer to H10W 15/00 and H10W 15/01 simultaneously>
D	H01L21/743	4	{Making of internal connections, substrate contacts}	<administrative transfer to H10W 20/021>
D	H01L21/746	4	{for AIII-BV integrated circuits}	<administrative transfer to H10W 15/00 and H10W 15/01 simultaneously>
D	H01L21/76	3	Making of isolation regions between components	<administrative transfer to H10W 10/01 and H10W 10/00 simultaneously>
D	H01L21/7602	4	{between components manufactured in an active substrate comprising SiC compounds}	<administrative transfer to H10W 10/01 and H10W 10/00 simultaneously>
D	H01L21/7605	4	{between components manufactured in an active substrate comprising AIII BV compounds}	<administrative transfer to H10W 10/01 and H10W 10/00 simultaneously>
D	H01L21/7607	4	{between components manufactured in an active substrate comprising A _{III} B _{VI} compounds}	<administrative transfer to H10W 10/01 and H10W 10/00 simultaneously>
D	H01L21/761	4	PN junctions	<administrative transfer to H10W 10/031 and H10W 10/30 simultaneously>
D	H01L21/762	4	Dielectric regions {, e.g. EPIC dielectric isolation, LOCOS; Trench refilling techniques, SOI technology, use of channel stoppers}	<administrative transfer to H10W 10/011 and H10W 10/10 simultaneously>

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D	H01L21/76202	5	{using a local oxidation of silicon, e.g. LOCOS, SWAMI, SILO (H01L21/76235 takes precedence; together with vertical isolation, e.g. LOCOS in a SOI substrate, H01L21/76264)}	<administrative transfer to H10W 10/012 and H10W 10/13 simultaneously>
D	H01L21/76205	6	{in a region being recessed from the surface, e.g. in a recess, groove, tub or trench region}	<administrative transfer to H10W 10/0121 and H10W 10/13 simultaneously>
D	H01L21/76208	7	{using auxiliary pillars in the recessed region, e.g. to form LOCOS over extended areas}	<administrative transfer to H10W 10/0123 and H10W 10/13 simultaneously>
D	H01L21/7621	7	{the recessed region having a shape other than rectangular, e.g. rounded or oblique shape (H01L21/76208 takes precedence)}	<administrative transfer to H10W 10/0124 and H10W 10/13 simultaneously>
D	H01L21/76213	6	{introducing electrical inactive or active impurities in the local oxidation region, e.g. to alter LOCOS oxide growth characteristics or for additional isolation purpose}	<administrative transfer to H10W 10/0125 and H10W 10/13 simultaneously>
D	H01L21/76216	7	{introducing electrical active impurities in the local oxidation region for the sole purpose of creating channel stoppers}	<administrative transfer to H10W 10/0126 and H10W 10/13 simultaneously>
D	H01L21/76218	8	{introducing both types of electrical active impurities in the local oxidation region for the sole purpose of creating channel stoppers, e.g. for isolation of complementary doped regions}	<administrative transfer to H10W 10/0127 and H10W 10/13 simultaneously>
D	H01L21/76221	6	{with a plurality of successive local oxidation steps}	<administrative transfer to H10W 10/0128 and H10W 10/13 simultaneously>
D	H01L21/76224	5	{using trench refilling with dielectric materials (trench filling with polycrystalline silicon H01L21/763; together with vertical isolation, e.g. trench refilling in a SOI substrate H01L21/76264)}	<administrative transfer to H10W 10/014 and H10W 10/17 simultaneously>
D	H01L21/76227	6	{the dielectric materials being obtained by full chemical transformation of non-dielectric materials, such as polycrystalline silicon, metals}	<administrative transfer to H10W 10/0142 and H10W 10/17 simultaneously>

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D	H01L21/76229	6	{Concurrent filling of a plurality of trenches having a different trench shape or dimension, e.g. rectangular and V-shaped trenches, wide and narrow trenches, shallow and deep trenches}	<administrative transfer to H10W 10/0143 and H10W 10/17 simultaneously>
D	H01L21/76232	6	{of trenches having a shape other than rectangular or V-shape, e.g. rounded corners, oblique or rounded trench walls (H01L21/76229 takes precedence)}	<administrative transfer to H10W 10/0145 and H10W 10/17 simultaneously>
D	H01L21/76235	7	{trench shape altered by a local oxidation of silicon process step, e.g. trench corner rounding by LOCOS}	<administrative transfer to H10W 10/0147 and H10W 10/17 simultaneously>
D	H01L21/76237	6	{introducing impurities in trench side or bottom walls, e.g. for forming channel stoppers or alter isolation behavior}	<administrative transfer to H10W 10/0148 and H10W 10/17 simultaneously>
D	H01L21/76264	6	{SOI together with lateral isolation, e.g. using local oxidation of silicon, or dielectric or polycrystalline material refilled trench or air gap isolation regions, e.g. completely isolated semiconductor islands}	<administrative transfer to H10P 90/1906, H10W 10/061 and H10W 10/181 simultaneously>
D	H01L21/76267	7	{Vertical isolation by silicon implanted buried insulating layers, e.g. oxide layers, i.e. SIMOX techniques}	<administrative transfer to H10P 90/1908, H10W 10/061 and H10W 10/181 simultaneously>
D	H01L21/7627	7	{Vertical isolation by full isolation by porous oxide silicon, i.e. FIPOS techniques}	<administrative transfer to H10P 90/191, H10W 10/061 and H10W 10/181 simultaneously>
D	H01L21/76272	7	{Vertical isolation by lateral overgrowth techniques, i.e. ELO techniques}	<administrative transfer to H10P 90/1912, H10W 10/061 and H10W 10/181 simultaneously>
D	H01L21/76275	7	{Vertical isolation by bonding techniques}	<administrative transfer to H10P 90/1914, H10W 10/061 and H10W 10/181 simultaneously>
D	H01L21/76278	7	{Vertical isolation by selective deposition of single crystal silicon, i.e. SEG techniques}	<administrative transfer to H10P 90/1912, H10W 10/061 and H10W 10/181 simultaneously>
D	H01L21/76281	7	{Lateral isolation by selective oxidation of silicon}	<administrative transfer to H10P 90/1906, H10W 10/012, H10W 10/061, H10W 10/13 and H10W 10/181 simultaneously>

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D	H01L21/76283	7	{Lateral isolation by refilling of trenches with dielectric material}	<administrative transfer to H10P 90/1906, H10W 10/014, H10W 10/061, H10W 10/17 and H10W 10/181 simultaneously>
D	H01L21/76286	7	{Lateral isolation by refilling of trenches with polycrystalline material}	<administrative transfer to H10P 90/1906, H10W 10/061, H10W 10/041, H10W 10/181 and H10W 10/40 simultaneously>
D	H01L21/76289	7	{Lateral isolation by air gap}	<administrative transfer to H10P 90/1906, H10W 10/061, H10W 10/021, H10W 10/181 and H10W 10/20 simultaneously>
D	H01L21/76291	7	{Lateral isolation by field effect}	<administrative transfer to H10P 90/1906, H10W 10/061, H10W 10/051, H10W 10/181 and H10W 10/50 simultaneously>
D	H01L21/76294	5	{using selective deposition of single crystal silicon, i.e. SEG techniques}	<administrative transfer to H10W 10/018 and H10W 10/10 simultaneously>
D	H01L21/76297	5	{Dielectric isolation using EPIC techniques, i.e. epitaxial passivated integrated circuit}	<administrative transfer to H10W 10/019 and H10W 10/10 simultaneously>
D	H01L21/763	4	Polycrystalline semiconductor regions {(H01L21/76264 takes precedence)}	<administrative transfer to H10W 10/041 and H10W 10/40 simultaneously>
D	H01L21/764	4	Air gaps {(H01L21/76264 takes precedence)}	<administrative transfer to H10W 10/021 and H10W 10/20 simultaneously>
D	H01L21/765	4	by field effect {(H01L21/76264 takes precedence)}	<administrative transfer to H10W 10/051 and H10W 10/50 simultaneously>
D	H01L21/768	3	Applying interconnections to be used for carrying current between separate components within a device {comprising conductors and dielectrics}	<administrative transfer to H10W 20/01>
D	H01L21/76801	4	{characterised by the formation and the after-treatment of the dielectrics, e.g. smoothing}	<administrative transfer to H10W 20/071>

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D	H01L21/76802	5	{by forming openings in dielectrics}	<administrative transfer to H10W 20/081>
D	H01L21/76804	6	{by forming tapered via holes}	<administrative transfer to H10W 20/082>
D	H01L21/76805	6	{the opening being a via or contact hole penetrating the underlying conductor}	<administrative transfer to H10W 20/083>
D	H01L21/76807	6	{for dual damascene structures}	<administrative transfer to H10W 20/084>
D	H01L21/76808	7	{involving intermediate temporary filling with material}	<administrative transfer to H10W 20/085>
D	H01L21/7681	7	{involving one or more buried masks}	<administrative transfer to H10W 20/086>
D	H01L21/76811	7	{involving multiple stacked pre-patterned masks}	<administrative transfer to H10W 20/087>
D	H01L21/76813	7	{involving a partial via etch}	<administrative transfer to H10W 20/088>
D	H01L21/76814	6	{post-treatment or after-treatment, e.g. cleaning or removal of oxides on underlying conductors}	<administrative transfer to H10W 20/081>
D	H01L21/76816	6	{Aspects relating to the layout of the pattern or to the size of vias or trenches (layout of the interconnections <u>per se</u> H01L 23/528; CAD of ICs G06F 30/00)}	<administrative transfer to H10W 20/089>
D	H01L21/76817	6	{using printing or stamping techniques}	<administrative transfer to H10W 20/091>
D	H01L21/76819	5	{Smoothing of the dielectric (planarisation of insulating materials <u>per se</u> H01L 21/31051)}	<administrative transfer to H10W 20/092>
D	H01L21/7682	5	{the dielectric comprising air gaps}	<administrative transfer to H10W 20/072 and

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				H10W 20/46 simultaneously>
D	H01L21/76822	5	{Modification of the material of dielectric layers, e.g. grading, a fter-treatment to improve the stability of the layers, to increase their density etc.}	<administrative transfer to H10W 20/093>
D	H01L21/76823	6	{transforming an insulating layer into a conductive layer}	<administrative transfer to H10W 20/094>
D	H01L21/76825	6	{by exposing the layer to particle radiation, e.g. ion implantation, irradiation with UV light or electrons etc. (plasma treatment H01L21/76826)}	<administrative transfer to H10W 20/095>
D	H01L21/76826	6	{by contacting the layer with gases, liquids or plasmas}	<administrative transfer to H10W 20/096>
D	H01L21/76828	6	{thermal treatment}	<administrative transfer to H10W 20/097>
D	H01L21/76829	5	{characterised by the formation of thin functional dielectric layers, e.g. dielectric etch-stop, barrier, capping or liner layers}	<administrative transfer to H10W 20/074>
D	H01L21/76831	6	{in via holes or trenches, e.g. non-conductive sidewall liners}	<administrative transfer to H10W 20/076>
D	H01L21/76832	6	{Multiple layers}	<administrative transfer to H10W 20/075>
D	H01L21/76834	6	{formation of thin insulating films on the sidewalls or on top of conductors (H01L21/76831 takes precedence)}	<administrative transfer to H10W 20/077>
D	H01L21/76835	5	{Combinations of two or more different dielectric layers having a low dielectric constant (H01L21/76832 takes precedence)}	<administrative transfer to H10W 20/071>
D	H01L21/76837	5	{Filling up the space between adjacent conductive structures; Gap-filling properties of dielectrics}	<administrative transfer to H10W 20/098>

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D	H01L21/76838	4	{characterised by the formation and the after-treatment of the conductors (etching for patterning the conductors H01L21/3213)}	<administrative transfer to H10W 20/031>
D	H01L21/7684	5	{Smoothing; Planarisation}	<administrative transfer to H10W 20/062>
D	H01L21/76841	5	{Barrier, adhesion or liner layers}	<administrative transfer to H10W 20/032>
D	H01L21/76843	6	{formed in openings in a dielectric}	<administrative transfer to H10W 20/033>
D	H01L21/76844	7	{Bottomless liners}	<administrative transfer to H10W 20/034>
D	H01L21/76846	7	{Layer combinations}	<administrative transfer to H10W 20/035>
D	H01L21/76847	7	{the layer being positioned within the main fill metal}	<administrative transfer to H10W 20/036>
D	H01L21/76849	7	{the layer being positioned on top of the main fill metal}	<administrative transfer to H10W 20/037>
D	H01L21/7685	6	{the layer covering a conductive structure (H01L21/76849 takes precedence)}	<administrative transfer to H10W 20/038>
D	H01L21/76852	7	{the layer also covering the sidewalls of the conductive structure}	<administrative transfer to H10W 20/039>
D	H01L21/76853	6	{characterized by particular after-treatment steps}	<administrative transfer to H10W 20/032>
D	H01L21/76855	7	{After-treatment introducing at least one additional element into the layer}	<administrative transfer to H10W 20/047>
D	H01L21/76856	8	{by treatment in plasmas or gaseous environments, e.g. nitriding a refractory metal liner}	<administrative transfer to H10W 20/048>

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D	H01L21/76858	8	{by diffusing alloying elements}	<administrative transfer to H10W 20/049>
D	H01L21/76859	8	{by ion implantation}	<administrative transfer to H10W 20/051>
D	H01L21/76861	7	{Post-treatment or after-treatment not introducing additional chemical elements into the layer}	<administrative transfer to H10W 20/052>
D	H01L21/76862	8	{Bombardment with particles, e.g. treatment in noble gas plasmas; UV irradiation}	<administrative transfer to H10W 20/0523>
D	H01L21/76864	8	{Thermal treatment}	<administrative transfer to H10W 20/0526>
D	H01L21/76865	7	{Selective removal of parts of the layer (H01L21/76844 takes precedence)}	<administrative transfer to H10W 20/054>
D	H01L21/76867	6	{characterized by methods of formation other than PVD, CVD or deposition from a liquids (PVD H01L21/2855; CVD H01L21/28556; deposition from liquids H01L21/288)}	<administrative transfer to H10W 20/055>
D	H01L21/76868	6	{Forming or treating discontinuous thin films, e.g. repair, enhancement or reinforcement of discontinuous thin films}	<administrative transfer to H10W 20/041>
D	H01L21/7687	6	{Thin films associated with contacts of capacitors}	<administrative transfer to H10W 20/046>
D	H01L21/76871	6	{Layers specifically deposited to enhance or enable the nucleation of further layers, i.e. seed layers}	<administrative transfer to H10W 20/042>
D	H01L21/76873	7	{for electroplating}	<administrative transfer to H10W 20/043>

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D	H01L21/76874	7	{for electroless plating}	<administrative transfer to H10W 20/044>
D	H01L21/76876	7	{for deposition from the gas phase, e.g. CVD}	<administrative transfer to H10W 20/045>
D	H01L21/76877	5	{Filling of holes, grooves or trenches, e.g. vias, with conductive material}	<administrative transfer to H10W 20/056>
D	H01L21/76879	6	{by selective deposition of conductive material in the vias, e.g. selective C.V.D. on semiconductor material, plating (plating on semiconductors in general H01L21/288)}	<administrative transfer to H10W 20/057>
D	H01L21/7688	6	{by deposition over sacrificial masking layer, e.g. lift-off (lift-off <u>per se</u> H01L 21/0272)}	<administrative transfer to H10W 20/058>
D	H01L21/76882	6	{Reflowing or applying of pressure to better fill the contact hole}	<administrative transfer to H10W 20/059>
D	H01L21/76883	6	{Post-treatment or after-treatment of the conductive material}	<administrative transfer to H10W 20/056>
D	H01L21/76885	5	{By forming conductive members before deposition of protective insulating material, e.g. pillars, studs}	<administrative transfer to H10W 20/063>
D	H01L21/76886	5	{Modifying permanently or temporarily the pattern or the conductivity of conductive members, e.g. formation of alloys, reduction of contact resistances}	<administrative transfer to H10W 20/064>
D	H01L21/76888	6	{By rendering at least a portion of the conductor non conductive, e.g. oxidation}	<administrative transfer to H10W 20/065>
D	H01L21/76889	6	{by forming silicides of refractory metals}	<administrative transfer to H10W 20/066>
D	H01L21/76891	6	{by using superconducting materials}	<administrative transfer to H10W 20/064>
D	H01L21/76892	6	{modifying the pattern}	<administrative transfer to H10W 20/067>

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D	H01L21/76894	7	{using a laser, e.g. laser cutting, laser direct writing, laser repair}	<administrative transfer to H10W 20/068>
D	H01L21/76895	5	{Local interconnects; Local pads, as exemplified by patent document EP0896365}	<administrative transfer to H10W 20/0698>
D	H01L21/76897	4	{Formation of self-aligned vias or contact plugs, i.e. involving a lithographically uncritical step}	<administrative transfer to H10W 20/069>
D	H01L21/76898	4	{formed through a semiconductor substrate}	<administrative transfer to H10W 20/023>
D	H01L23/00	0	Details of semiconductor or other solid state devices (H01L25/00 takes precedence {; structural arrangements for testing or measuring during manufacture or treatment, or for reliability measurements H01L22/00; arrangements for connecting or disconnecting semiconductor or solid-state bodies, or methods related thereto H01L24/00; finger print sensors G06V40/12})	<administrative transfer to H10W 99/00>
D	H01L23/02	1	Containers; Seals (H01L 23/12, H01L 23/34, H01L 23/48, H01L 23/552, {H01L 23/66} take precedence; {for memories G11C})	<administrative transfer to H10W 76/10>
D	H01L23/04	2	characterised by the shape {of the container or parts, e.g. caps, walls}	<administrative transfer to H10W 76/12>
D	H01L23/041	3	{the container being a hollow construction having no base used as a mounting for the semiconductor body}	<administrative transfer to H10W 76/161>

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D	H01L23/043	3	the container being a hollow construction and having a conductive base as a mounting as well as a lead for the semiconductor body	<administrative transfer to H10W 76/13>
D	H01L23/045	4	the other leads having an insulating passage through the base	<administrative transfer to H10W 76/132>
D	H01L23/047	4	the other leads being parallel to the base	<administrative transfer to H10W 76/134>
D	H01L23/049	4	the other leads being perpendicular to the base	<administrative transfer to H10W 76/136>
D	H01L23/051	4	another lead being formed by a cover plate parallel to the baseplate, e.g. sandwich type	<administrative transfer to H10W 76/138>
D	H01L23/053	3	the container being a hollow construction and having an insulating {or insulated} base as a mounting for the semiconductor body	<administrative transfer to H10W 76/15>
D	H01L23/055	4	the leads having a passage through the base {(H01L23/057 takes precedence)}	<administrative transfer to H10W 76/153>
D	H01L23/057	4	the leads being parallel to the base	<administrative transfer to H10W 76/157>
D	H01L23/06	2	characterised by the material of the container or its electrical properties	<administrative transfer to H10W 76/17>
D	H01L23/08	3	the material being an electrical insulator, e.g. glass	<administrative transfer to H10W 76/18>
D	H01L23/10	2	characterised by the material or arrangement of seals between parts, e.g. between cap and base of the container or between leads and walls of the container	<administrative transfer to H10W 76/60>
D	H01L23/12	1	Mountings, e.g. non-detachable insulating substrates	<administrative transfer to H10W 70/60>
D	H01L23/13	2	characterised by the shape	<administrative transfer to H10W 70/68>
D	H01L23/14	2	characterised by the material or its electrical properties {(printed circuit boards H05K1/00)}	<administrative transfer to H10W 70/69>
D	H01L23/142	3	{Metallic substrates having insulating layers}	<administrative transfer to H10W 70/6875>
D	H01L23/145	3	{Organic substrates, e.g. plastic}	<administrative transfer to H10W 70/695>

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D	H01L23/147	3	{Semiconductor insulating substrates (semiconductor conductive substrates H01L23/4926)}	<administrative transfer to H10W 70/698>
D	H01L23/15	3	Ceramic or glass substrates {(H01L23/142, H01L23/145, H01L23/147 take precedence)}	<administrative transfer to H10W 70/692>
D	H01L23/16	1	Fillings or auxiliary members in containers {or encapsulations}, e.g. centering rings (H01L23/42, H01L23/552 take precedence)	<administrative transfer to H10W 76/40>
D	H01L23/18	2	Fillings characterised by the material, its physical or chemical properties, or its arrangement within the complete device	<administrative transfer to H10W 76/42>
D	H01L23/20	3	gaseous at the normal operating temperature of the device	<administrative transfer to H10W 76/43>
D	H01L23/22	3	liquid at the normal operating temperature of the device	<administrative transfer to H10W 76/45>
D	H01L23/24	3	solid or gel at the normal operating temperature of the device {(H01L23/3135 takes precedence)}	<administrative transfer to H10W 76/47>
D	H01L23/26	3	including materials for absorbing or reacting with moisture or other undesired substances {, e.g. getters}	<administrative transfer to H10W 76/48>
D	H01L23/28	1	Encapsulations, e.g. encapsulating layers, coatings, {e.g. for protection} (H01L 23/552 takes precedence; {insulating layers for contacts or interconnections H01L 23/5329})	<administrative transfer to H10W 74/00>

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D	H01L23/29	2	characterised by the material {, e.g. carbon (interlayer dielectrics H01L23/5329)}	<administrative transfer to H10W 74/40>
D	H01L23/291	3	{Oxides or nitrides or carbides, e.g. ceramics, glass}	<administrative transfer to H10W 74/43>
D	H01L23/293	3	{Organic, e.g. plastic}	<administrative transfer to H10W 74/47>
D	H01L23/295	4	{containing a filler (H01L23/296 takes precedence)}	<administrative transfer to H10W 74/473>
D	H01L23/296	4	{Organo-silicon compounds}	<administrative transfer to H10W 74/476>
D	H01L23/298	3	{Semiconductor material, e.g. amorphous silicon}	<administrative transfer to H10W 74/481>
D	H01L23/31	2	characterised by the arrangement {or shape}	<administrative transfer to H10W 74/10>
D	H01L23/3107	3	{the device being completely enclosed}	<administrative transfer to H10W 74/111>
D	H01L23/3114	4	{the device being a chip scale package, e.g. CSP}	<administrative transfer to H10W 74/129>
D	H01L23/3121	4	{a substrate forming part of the encapsulation}	<administrative transfer to H10W 74/114>
D	H01L23/3128	5	{the substrate having spherical bumps for external connection}	<administrative transfer to H10W 74/117>
D	H01L23/3135	4	{Double encapsulation or coating and encapsulation}	<administrative transfer to H10W 74/121>
D	H01L23/3142	4	{Sealing arrangements between parts, e.g. adhesion promoters}	<administrative transfer to H10W 74/127>

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D	H01L23/315	4	{the encapsulation having a cavity}	<administrative transfer to H10W 74/124>
D	H01L23/3157	3	{Partial encapsulation or coating (mask layer used as insulation layer H01L21/31)}	<administrative transfer to H10W 74/131>
D	H01L23/3164	4	{the coating being a foil}	<administrative transfer to H10W 74/144>
D	H01L23/3171	4	{the coating being directly applied to the semiconductor body, e.g. passivation layer (H01L23/3178 takes precedence)}	<administrative transfer to H10W 74/137>
D	H01L23/3178	4	{Coating or filling in grooves made in the semiconductor body}	<administrative transfer to H10W 74/134>
D	H01L23/3185	4	{the coating covering also the sidewalls of the semiconductor body}	<administrative transfer to H10W 74/141>
D	H01L23/3192	4	{Multilayer coating}	<administrative transfer to H10W 74/147>
D	H01L23/32	1	Holders for supporting the complete device in operation, i.e. detachable fixtures (H01L23/40 takes precedence)	<administrative transfer to H10W 78/00>
D	H01L23/34	1	Arrangements for cooling, heating, ventilating or temperature compensation {; Temperature sensing arrangements (thermal treatment apparatus H01L21/00)}	<administrative transfer to H10W 40/00>
D	H01L23/345	2	{Arrangements for heating (thermal treatment apparatus H01L21/00)}	<administrative transfer to H10W 40/10>

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D	H01L23/36	2	Selection of materials, or shaping, to facilitate cooling or heating, e.g. heatsinks {(H01L23/28, H01L23/40, H01L23/42, H01L23/44, H01L23/46 take precedence; heating H01L23/345)}	<administrative transfer to H10W 40/10>
D	H01L23/367	3	Cooling facilitated by shape of device {(H01L23/38, H01L23/40, H01L23/42, H01L23/44, H01L23/46 take precedence)}	<administrative transfer to H10W 40/22>
D	H01L23/3672	4	{Foil-like cooling fins or heat sinks (being part of lead-frames H01L23/49568)}	<administrative transfer to H10W 40/226>
D	H01L23/3675	4	{characterised by the shape of the housing}	<administrative transfer to H10W 40/22>
D	H01L23/3677	4	{Wire-like or pin-like cooling fins or heat sinks}	<administrative transfer to H10W 40/228>
D	H01L23/373	3	Cooling facilitated by selection of materials for the device {or materials for thermal expansion adaptation, e.g. carbon}	<administrative transfer to H10W 40/25>

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D	H01L23/3731	4	{Ceramic materials or glass (H01L23/3732, H01L23/3733, H01L23/3735, H01L23/3737, H01L23/3738 take precedence)}	<administrative transfer to H10W 40/259>
D	H01L23/3732	4	{Diamonds}	<administrative transfer to H10W 40/254>
D	H01L23/3733	4	{having a heterogeneous or anisotropic structure, e.g. powder or fibres in a matrix, wire mesh, porous structures (H01L23/3732, H01L23/3737 take precedence)}	<administrative transfer to H10W 40/257>
D	H01L23/3735	4	{Laminates or multilayers, e.g. direct bond copper ceramic substrates}	<administrative transfer to H10W 40/255>
D	H01L23/3736	4	{Metallic materials (H01L23/3732, H01L23/3733, H01L23/3735, H01L23/3737, H01L23/3738 take precedence)}	<administrative transfer to H10W 40/258>
D	H01L23/3737	4	{Organic materials with or without a thermoconductive filler}	<administrative transfer to H10W 40/251>
D	H01L23/3738	4	{Semiconductor materials}	<administrative transfer to H10W 40/253>
D	H01L23/38	2	Cooling arrangements using the Peltier effect	<administrative transfer to H10W 40/28>

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D	H01L23/40	2	Mountings or securing means for detachable cooling or heating arrangements {(heating H01L23/345); fixed by friction, plugs or springs}	<administrative transfer to H10W 40/60>
D	H01L23/4006	3	{with bolts or screws}	<administrative transfer to H10W 40/611>
D	H01L23/4012	4	{for stacked arrangements of a plurality of semiconductor devices (assemblies <u>per se</u> H01L 25/00)}	<administrative transfer to H10W 40/613>
D	H01L23/4018	4	{characterised by the type of device to be heated or cooled}	<administrative transfer to H10W 40/611>
D	H01L23/4025	5	{Base discrete devices, e.g. presspack, disc-type transistors}	<administrative transfer to H10W 40/611>
D	H01L23/4031	5	{Packaged discrete devices, e.g. to-3 housings, diodes}	<administrative transfer to H10W 40/611>
D	H01L23/4037	4	{characterised by thermal path or place of attachment of heatsink}	<administrative transfer to H10W 40/231>
D	H01L23/4043	5	{heatsink to have chip}	<administrative transfer to H10W 40/233>
D	H01L23/405	5	{heatsink to package}	<administrative transfer to H10W 40/235>
D	H01L23/4056	5	{heatsink to additional heatsink}	<administrative transfer to H10W 40/237>
D	H01L23/4062	5	{heatsink to or through board or cabinet}	<administrative transfer to H10W 40/231>
D	H01L23/4068	5	{Heatconductors between device and heatsink, e.g. compliant heat-spreaders, heat-conducting bands}	<administrative transfer to H10W 40/242>
D	H01L23/4075	4	{Mechanical elements}	<administrative transfer to H10W 40/60>

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D	H01L2023/4081	5	{Compliant clamping elements not primarily serving heat-conduction}	<administrative transfer to H10W 40/625>
D	H01L2023/4087	5	{Mounting accessories, interposers, clamping or screwing parts}	<administrative transfer to H10W 40/60>
D	H01L23/4093	3	{Snap-on arrangements, e.g. clips}	<administrative transfer to H10W 40/641>
D	H01L23/42	2	Fillings or auxiliary members in containers {or encapsulations} selected or arranged to facilitate heating or cooling	<administrative transfer to H10W 40/70>
D	H01L23/427	3	Cooling by change of state, e.g. use of heat pipes {(by liquefied gas H01L23/445)}	<administrative transfer to H10W 40/73>
D	H01L23/4275	4	{by melting or evaporation of solids}	<administrative transfer to H10W 40/735>
D	H01L23/433	3	Auxiliary members {in containers} characterised by their shape, e.g. pistons	<administrative transfer to H10W 40/77>
D	H01L23/4332	4	{Bellows}	<administrative transfer to H10W 40/772>
D	H01L23/4334	4	{Auxiliary members in encapsulations (H01L23/49568 takes precedence)}	<administrative transfer to H10W 40/778>
D	H01L23/4336	4	{in combination with jet impingement}	<administrative transfer to H10W 40/776>
D	H01L23/4338	4	{Pistons, e.g. spring-loaded members}	<administrative transfer to H10W 40/774>
D	H01L23/44	2	the complete device being wholly immersed in a fluid other than air {(H01L23/427 takes precedence)}	<administrative transfer to H10W 40/30>
D	H01L23/445	3	{the fluid being a liquefied gas, e.g. in a cryogenic vessel}	<administrative transfer to H10W 40/305>

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D	H01L23/46	2	involving the transfer of heat by flowing fluids (H01L23/42, H01L23/44 take precedence)	<administrative transfer to H10W 40/40>
D	H01L23/467	3	by flowing gases, e.g. air {(H01L23/473 takes precedence)}	<administrative transfer to H10W 40/43>
D	H01L23/473	3	by flowing liquids {(H01L23/4332, H01L23/4338 take precedence)}	<administrative transfer to H10W 40/47>
D	H01L23/4735	4	{Jet impingement (H01L23/4336 takes precedence)}	<administrative transfer to H10W 40/475>
D	H01L23/48	1	Arrangements for conducting electric current to or from the solid state body in operation, e.g. leads, terminal arrangements {}; Selection of materials therefor}	<administrative transfer to H10W 72/00>
D	H01L23/481	2	{Internal lead connections, e.g. via connections, feedthrough structures}	<administrative transfer to H10W 20/20>
D	H01L23/482	2	consisting of lead-in layers inseparably applied to the semiconductor body {(electrodes)}	<administrative transfer to H10W 20/40>
D	H01L23/4821	3	{Bridge structure with air gap}	<administrative transfer to H10W 20/483>
D	H01L23/4822	3	{Beam leads}	<administrative transfer to H10W 72/60>
D	H01L23/4824	3	{Pads with extended contours, e.g. grid structure, branch structure, finger structure}	<administrative transfer to H10W 20/484>
D	H01L23/4825	3	{for devices consisting of semiconductor layers on insulating or semi-insulating substrates, e.g. silicon on sapphire devices, i.e. SOS}	<administrative transfer to H10W 20/40>

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D	H01L23/4827	3	{Materials}	<administrative transfer to H10W 20/40>
D	H01L23/4828	4	{Conductive organic material or pastes, e.g. conductive adhesives, inks}	<administrative transfer to H10W 20/40>
D	H01L23/485	3	consisting of layered constructions comprising conductive layers and insulating layers, e.g. planar contacts {(H01L23/4821, H01L23/4822, H01L23/4824, H01L23/4825 take precedence; materials H01L23/532, bond pads H01L24/02, bump connectors H01L24/10)}	<administrative transfer to H10W 20/40>
D	H01L23/4855	4	{Overhang structure}	<administrative transfer to H10W 20/40>
D	H01L23/488	2	consisting of soldered {or bonded} constructions {(bump connectors H01L24/01)}	<administrative transfer to H10W 72/20>
D	H01L23/49	3	wire-like {arrangements or pins or rods (using optical fibres H01L23/48; pins attached to insulating substrates H01L23/49811)}	<administrative transfer to H10W 72/50>
D	H01L23/492	3	Bases or plates {or solder therefor}	<administrative transfer to H10W 70/20>
D	H01L23/4922	4	{having a heterogeneous or anisotropic structure}	<administrative transfer to H10W 70/22>

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D	H01L23/4924	4	{characterised by the materials}	<administrative transfer to H10W 70/24>
D	H01L23/4926	5	{the materials containing semiconductor material}	<administrative transfer to H10W 70/26>
D	H01L23/4928	5	{the materials containing carbon}	<administrative transfer to H10W 70/28>
D	H01L23/495	3	Lead-frames {or other flat leads (H01L23/498 takes precedence; lead frame interconnections between components H01L23/52)}	<administrative transfer to H10W 70/40>
D	H01L23/49503	4	{characterised by the die pad}	<administrative transfer to H10W 70/411>
D	H01L23/49506	5	{an insulative substrate being used as a diepad, e.g. ceramic, plastic (H01L23/49531 takes precedence)}	<administrative transfer to H10W 70/413>
D	H01L23/4951	5	{Chip-on-leads or leads-on-chip techniques, i.e. inner lead fingers being used as die pad}	<administrative transfer to H10W 70/415>
D	H01L23/49513	5	{having bonding material between chip and die pad}	<administrative transfer to H10W 70/417>
D	H01L23/49517	4	{Additional leads}	<administrative transfer to H10W 70/464>
D	H01L23/4952	5	{the additional leads being a bump or a wire}	<administrative transfer to H10W 70/465>
D	H01L23/49524	5	{the additional leads being a tape carrier or flat leads}	<administrative transfer to H10W 70/466>
D	H01L23/49527	5	{the additional leads being a multilayer}	<administrative transfer to H10W 70/467>
D	H01L23/49531	5	{the additional leads being a wiring board}	<administrative transfer to H10W 70/468>

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D	H01L23/49534	4	{Multi-layer}	<administrative transfer to H10W 70/451>
D	H01L23/49537	4	{Plurality of lead frames mounted in one device}	<administrative transfer to H10W 70/442>
D	H01L23/49541	4	{Geometry of the lead-frame}	<administrative transfer to H10W 70/421>
D	H01L23/49544	5	{Deformation absorbing parts in the lead frame plane, e.g. meanderline shape (H01L23/49562 takes precedence)}	<administrative transfer to H10W 70/433>
D	H01L23/49548	5	{Cross section geometry (H01L23/49562 takes precedence)}	<administrative transfer to H10W 70/424>
D	H01L23/49551	6	{characterised by bent parts}	<administrative transfer to H10W 70/427>
D	H01L23/49555	7	{the bent parts being the outer leads}	<administrative transfer to H10W 70/429>
D	H01L23/49558	5	{Insulating layers on lead frames, e.g. bridging members}	<administrative transfer to H10W 70/435>
D	H01L23/49562	5	{for individual devices of subclass H10D}	<administrative transfer to H10W 70/481>
D	H01L23/49565	5	{Side rails of the lead frame, e.g. with perforations, sprocket holes}	<administrative transfer to H10W 70/438>
D	H01L23/49568	4	{specifically adapted to facilitate heat dissipation}	<administrative transfer to H10W 70/461>
D	H01L23/49572	4	{consisting of thin flexible metallic tape with or without a film carrier (H01L23/49503 - H01L23/49568 and H01L23/49575 - H01L23/49579 take precedence)}	<administrative transfer to H10W 70/453>

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D	H01L23/49575	4	{Assemblies of semiconductor devices on lead frames}	<administrative transfer to H10W 90/811>
D	H01L23/49579	4	{characterised by the materials of the lead frames or layers thereon}	<administrative transfer to H10W 70/456>
D	H01L23/49582	5	{Metallic layers on lead frames}	<administrative transfer to H10W 70/457>
D	H01L23/49586	5	{Insulating layers on lead frames}	<administrative transfer to H10W 70/458>
D	H01L23/49589	4	{Capacitor integral with or on the lead frame}	<administrative transfer to H10W 70/475>
D	H01L23/49593	4	{Battery in combination with a lead frame}	<administrative transfer to H10W 70/474>
D	H01L23/49596	4	{Oscillators in combination with lead-frames}	<administrative transfer to H10W 70/476>
D	H01L23/498	3	Leads, {i.e. metallisations or lead-frames} on insulating substrates, {e.g. chip carriers (shape of the substrate H01L23/13)}	<administrative transfer to H10W 70/60>
D	H01L23/49805	4	{the leads being also applied on the sidewalls or the bottom of the substrate, e.g. leadless packages for surface mounting}	<administrative transfer to H10W 70/657>
D	H01L23/49811	4	{Additional leads joined to the metallisation on the insulating substrate, e.g. pins, bumps, wires, flat leads (H01L23/49827 takes precedence)}	<administrative transfer to H10W 90/701>
D	H01L23/49816	5	{Spherical bumps on the substrate for external connection, e.g. ball grid arrays [BGA]}	<administrative transfer to H10W 90/701>
D	H01L23/49822	4	{Multilayer substrates (multilayer metallisation on monolayer substrate H01L23/498)}	<administrative transfer to H10W 70/685>

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D	H01L23/49827	4	{Via connections through the substrates, e.g. pins going through the substrate, coaxial cables (H01L23/49822, H01L23/49833, H01L23/4985, H01L23/49861 take precedence)}	<administrative transfer to H10W 70/635>
D	H01L23/49833	4	{the chip support structure consisting of a plurality of insulating substrates}	<administrative transfer to H10W 90/401>
D	H01L23/49838	4	{Geometry or layout}	<administrative transfer to H10W 70/65>
D	H01L23/49844	5	{for individual devices of subclass H10D}	<administrative transfer to H10W 70/658>
D	H01L23/4985	4	{Flexible insulating substrates (H01L23/49572 and H01L23/49855 take precedence)}	<administrative transfer to H10W 70/688>
D	H01L23/49855	4	{for flat-cards, e.g. credit cards (cards <u>per se</u> G06K 19/00)}	<administrative transfer to H10W 70/699>
D	H01L23/49861	4	{Lead-frames fixed on or encapsulated in insulating substrates (H01L23/4985, H01L23/49805 take precedence)}	<administrative transfer to H10W 70/479>
D	H01L23/49866	4	{characterised by the materials (materials of the substrates H01L23/14, of the lead-frames H01L23/49579)}	<administrative transfer to H10W 70/66>

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D	H01L23/49872	5	{the conductive materials containing semiconductor material}	<administrative transfer to H10W 70/662>
D	H01L23/49877	5	{Carbon, e.g. fullerenes (superconducting fullerenes H10N60/853)}	<administrative transfer to H10W 70/664>
D	H01L23/49883	5	{the conductive materials containing organic materials or pastes, e.g. for thick films (for printed circuits H05K1/092)}	<administrative transfer to H10W 70/666>
D	H01L23/49888	5	{the conductive materials containing superconducting material}	<administrative transfer to H10W 70/668>
D	H01L23/49894	5	{Materials of the insulating layers or coatings}	<administrative transfer to H10W 70/69>
D	H01L23/50	2	for integrated circuit devices, {e.g. power bus, number of leads}(H01L23/482 - H01L23/498 take precedence)	<administrative transfer to H10W 72/00>
D	H01L23/52	1	Arrangements for conducting electric current within the device in operation from one component to another {, i.e. interconnections, e.g. wires, lead frames (optical interconnections G02B6/00)}	<administrative transfer to H10W 72/00>
D	H01L23/522	2	including external interconnections consisting of a multilayer structure of conductive and insulating layers inseparably formed on the semiconductor body	<administrative transfer to H10W 20/40>
D	H01L23/5221	3	{Crossover interconnections}	<administrative transfer to H10W 20/432>
D	H01L23/5222	3	{Capacitive arrangements or effects of, or between wiring layers (other capacitive arrangements H01L23/642)}	<administrative transfer to H10W 20/495>
D	H01L23/5223	4	{Capacitor integral with wiring layers}	<administrative transfer to H10W 20/496>

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D	H01L23/5225	4	{Shielding layers formed together with wiring layers}	<administrative transfer to H10W 20/423>
D	H01L23/5226	3	{Via connections in a multilevel interconnection structure}	<administrative transfer to H10W 20/42>
D	H01L23/5227	3	{Inductive arrangements or effects of, or between, wiring layers (other inductive arrangements H01L23/645)}	<administrative transfer to H10W 20/497>
D	H01L23/5228	3	{Resistive arrangements or effects of, or between, wiring layers (other resistive arrangements H01L23/647)}	<administrative transfer to H10W 20/498>
D	H01L23/525	3	with adaptable interconnections	<administrative transfer to H10W 20/49>
D	H01L23/5252	4	{comprising anti-fuses, i.e. connections having their state changed from non-conductive to conductive}	<administrative transfer to H10W 20/491>
D	H01L23/5254	5	{the change of state resulting from the use of an external beam, e.g. laser beam or ion beam}	<administrative transfer to H10W 20/492>
D	H01L23/5256	4	{comprising fuses, i.e. connections having their state changed from conductive to non-conductive}	<administrative transfer to H10W 20/493>
D	H01L23/5258	5	{the change of state resulting from the use of an external beam, e.g. laser beam or ion beam}	<administrative transfer to H10W 20/494>
D	H01L23/528	3	Layout of the interconnection structure	<administrative transfer to H10W 20/43>
D	H01L23/5283	4	{Cross-sectional geometry}	<administrative transfer to H10W 20/435>
D	H01L23/5286	4	{Arrangements of power or ground buses}	<administrative transfer to H10W 20/427>
D	H01L23/532	3	characterised by the materials	<administrative transfer to H10W 20/48>
D	H01L23/53204	4	{Conductive materials}	<administrative transfer to H10W 20/44>

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D	H01L23/53209	5	{based on metals, e.g. alloys, metal silicides (H01L23/53285 takes precedence)}	<administrative transfer to H10W 20/4403>
D	H01L23/53214	6	{the principal metal being a luminiun}	<administrative transfer to H10W 20/4405>
D	H01L23/53219	7	{Aluminium alloys}	<administrative transfer to H10W 20/4407>
D	H01L23/53223	7	{Additional layers associated with a luminiun layers, e.g. adhesion, barrier, cladding layers}	<administrative transfer to H10W 20/425>
D	H01L23/53228	6	{the principal metal being copper}	<administrative transfer to H10W 20/4421>
D	H01L23/53233	7	{Copper alloys}	<administrative transfer to H10W 20/4424>
D	H01L23/53238	7	{Additional layers associated with copper layers, e.g. adhesion, barrier, cladding layers}	<administrative transfer to H10W 20/425>
D	H01L23/53242	6	{the principal metal being a noble metal, e.g. gold}	<administrative transfer to H10W 20/4432>
D	H01L23/53247	7	{Noble-metal alloys}	<administrative transfer to H10W 20/4435>
D	H01L23/53252	7	{Additional layers associated with noble-metal layers, e.g. adhesion, barrier, cladding layers}	<administrative transfer to H10W 20/425>
D	H01L23/53257	6	{the principal metal being a refractory metal}	<administrative transfer to H10W 20/4441>
D	H01L23/53261	7	{Refractory-metal alloys}	<administrative transfer to H10W 20/4446>
D	H01L23/53266	7	{Additional layers associated with refractory-metal layers, e.g. adhesion, barrier, cladding layers}	<administrative transfer to H10W 20/425>
D	H01L23/53271	5	{containing semiconductor material, e.g. polysilicon}	<administrative transfer to H10W 20/4451>

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D	H01L23/53276	5	{containing carbon, e.g. fullerenes (superconducting fullerenes H10N60/853)}	<administrative transfer to H10W 20/4462>
D	H01L23/5328	5	{containing conductive organic materials or pastes, e.g. conductive adhesives, inks}	<administrative transfer to H10W 20/4473>
D	H01L23/53285	5	{containing superconducting materials}	<administrative transfer to H10W 20/4484>
D	H01L23/5329	4	{Insulating materials}	<administrative transfer to H10W 20/48>
D	H01L23/53295	5	{Stacked insulating layers}	<administrative transfer to H10W 20/47>
D	H01L23/535	2	including internal interconnections, e.g. cross-under constructions {(internal lead connections H01L23/481)}	<administrative transfer to H10W 20/20>
D	H01L23/538	2	the interconnection structure between a plurality of semiconductor chips being formed on, or in, insulating substrates ({H05K takes precedence; manufacture or treatment H01L 21/4846} ; mountings <u>per se</u> H01L 23/12; {materials H01L 23/49866})	<administrative transfer to H10W 70/60 and H10W 70/611 simultaneously>
D	H01L23/5381	3	{Crossover interconnections, e.g. bridge stepovers}	<administrative transfer to H10W 70/65>
D	H01L23/5382	3	{Adaptable interconnections, e.g. for engineering changes}	<administrative transfer to H10W 70/641 and H10W 70/611 simultaneously>
D	H01L23/5383	3	{Multilayer substrates (H01L23/5385 takes precedence; multilayer metallisation on monolayer substrates H01L23/538)}	<administrative transfer to H10W 70/685 and H10W 70/611 simultaneously>

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D	H01L23/5384	3	{Conductive vias through the substrate with or without pins, e.g. buried coaxial conductors (H01L23/5383, H01L23/5385 take precedence; pins attached to insulating substrates H01L23/49811)}	<administrative transfer to H10W 70/635 and H10W 70/611 simultaneously>
D	H01L23/5385	3	{Assembly of a plurality of insulating substrates}	<administrative transfer to H10W 70/611 and H10W 90/401 simultaneously>
D	H01L23/5386	3	{Geometry or layout of the interconnection structure}	<administrative transfer to H10W 70/65 and H10W 70/611 simultaneously>
D	H01L23/5387	3	{Flexible insulating substrates (H01L23/5388 takes precedence)}	<administrative transfer to H10W 70/688 and H10W 70/611 simultaneously>
D	H01L23/5388	3	{for flat cards, e.g. credit cards (cards <u>per se</u> G06K 19/00)}	<administrative transfer to H10W 70/699 and H10W 70/611 simultaneously>
D	H01L23/5389	3	{the chips being integrally enclosed by the interconnect and support structures}	<administrative transfer to H10W 70/614>
D	H01L23/544	1	Marks applied to semiconductor devices {or parts}, e.g. registration marks, {alignment structures, wafer maps (test patterns for characterising or monitoring manufacturing processes H01L22/00)}	<administrative transfer to H10W 46/00>
D	H01L23/552	1	Protection against radiation, e.g. light {or electromagnetic waves}	<administrative transfer to H10W 42/20>
D	H01L23/556	2	against alpha rays	<administrative transfer to H10W 42/25>

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D	H01L23/562	1	{Protection against mechanical damage (H01L23/02, H01L23/28 take precedence)}	<administrative transfer to H10W 42/121>
D	H01L23/564	1	{Details not otherwise provided for, e.g. protection against moisture (getters H01L23/26)}	<administrative transfer to H10W 42/00>
D	H01L23/57	1	{Protection from inspection, reverse engineering or tampering}	<administrative transfer to H10W 42/40>
D	H01L23/573	2	{using passive means}	<administrative transfer to H10W 42/40>
D	H01L23/576	2	{using active circuits}	<administrative transfer to H10W 42/405>
D	H01L23/58	1	Structural electrical arrangements for semiconductor devices not otherwise provided for {, e.g. in combination with batteries (H01L23/49593, H01L23/49596 take precedence)}	<administrative transfer to H10W 42/00>
D	H01L23/585	2	{comprising conductive layers or plates or strips or rods or rings (H01L23/60, H01L23/62, H01L23/64, H01L23/66 take precedence)}	<administrative transfer to H10W 42/00>
D	H01L23/60	2	Protection against electrostatic charges or discharges, e.g. Faraday shields	<administrative transfer to H10W 42/60>
D	H01L23/62	2	Protection against overvoltage, e.g. fuses, shunts	<administrative transfer to H10W 42/80>
D	H01L23/64	2	Impedance arrangements	<administrative transfer to H10W 44/00>

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D	H01L23/642	3	{Capacitive arrangements (H01L23/49589, H01L23/645, H01L23/647, H01L23/66 take precedence; capacitive effects between wiring layers on the semiconductor body H01L23/5222)}	<administrative transfer to H10W 44/601>
D	H01L23/645	3	{Inductive arrangements (H01L23/647, H01L23/66 take precedence)}	<administrative transfer to H10W 44/501>
D	H01L23/647	3	{Resistive arrangements (H01L23/66, H01L23/62 take precedence)}	<administrative transfer to H10W 44/401>
D	H01L23/66	3	High-frequency adaptations	<administrative transfer to H10W 44/20>
D	H01L24/00	0	{Arrangements for connecting or disconnecting semiconductor or solid-state bodies; Methods or apparatus related thereto}	<administrative transfer to H10W 72/00>
D	H01L24/01	1	{Means for bonding being attached to, or being formed on, the surface to be connected, e.g. chip-to-package, die-attach, "first-level" interconnects; Manufacturing methods related thereto}	<administrative transfer to H10W 72/00>

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D	H01L24/02	2	{Bonding areas (on insulating substrates, e.g. chip carriers, H01L23/49816, H01L23/49838, H01L23/5389); Manufacturing methods related thereto}	<administrative transfer to H10W 72/90>
D	H01L24/03	3	{Manufacturing methods}	<administrative transfer to H10W 72/019>
D	H01L24/04	3	{Structure, shape, material or disposition of the bonding areas prior to the connecting process}	<administrative transfer to H10W 72/90>
D	H01L24/05	4	{of an individual bonding area }	<administrative transfer to H10W 72/90>
D	H01L24/06	4	{of a plurality of bonding areas}	<administrative transfer to H10W 72/90>
D	H01L24/07	3	{Structure, shape, material or disposition of the bonding areas after the connecting process}	<administrative transfer to H10W 72/90>
D	H01L24/08	4	{of an individual bonding area }	<administrative transfer to H10W 72/90>
D	H01L24/09	4	{of a plurality of bonding areas}	<administrative transfer to H10W 72/90>
D	H01L24/10	2	{Bump connectors (bumps on insulating substrates, e.g. chip carriers, H01L23/49816); Manufacturing methods related thereto}	<administrative transfer to H10W 72/20>
D	H01L24/11	3	{Manufacturing methods (for bumps on insulating substrates H01L21/4853)}	<administrative transfer to H10W 72/012>

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D	H01L24/12	3	{Structure, shape, material or disposition of the bump connectors prior to the connecting process}	<administrative transfer to H10W 72/20>
D	H01L24/13	4	{of an individual bump connector}	<administrative transfer to H10W 72/20>
D	H01L24/14	4	{of a plurality of bump connectors}	<administrative transfer to H10W 72/20>
D	H01L24/15	3	{Structure, shape, material or disposition of the bump connectors after the connecting process}	<administrative transfer to H10W 72/20>
D	H01L24/16	4	{of an individual bump connector}	<administrative transfer to H10W 72/20>
D	H01L24/17	4	{of a plurality of bump connectors}	<administrative transfer to H10W 72/20>
D	H01L24/18	2	{High density interconnect [HDI] connectors; Manufacturing methods related thereto (interconnection structure between a plurality of semiconductor chips H01L23/5389)}	<administrative transfer to H10W 70/60>
D	H01L24/19	3	{Manufacturing methods of high density interconnect preforms}	<administrative transfer to H10W 70/09>
D	H01L24/20	3	{Structure, shape, material or disposition of high density interconnect preforms}	<administrative transfer to H10W 70/60>
D	H01L24/23	3	{Structure, shape, material or disposition of the high density interconnect connectors after the connecting process}	<administrative transfer to H10W 70/60>
D	H01L24/24	4	{of an individual high density interconnect connector}	<administrative transfer to H10W 70/60>
D	H01L24/25	4	{of a plurality of high density interconnect connectors}	<administrative transfer to H10W 70/60>
D	H01L24/26	2	{Layer connectors, e.g. plate connectors, solder or adhesive layers; Manufacturing methods related thereto}	<administrative transfer to H10W 72/30>

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D	H01L24/27	3	{Manufacturing methods}	<administrative transfer to H10W 72/013>
D	H01L24/28	3	{Structure, shape, material or disposition of the layer connectors prior to the connecting process}	<administrative transfer to H10W 72/30>
D	H01L24/29	4	{of an individual layer connector}	<administrative transfer to H10W 72/30>
D	H01L24/30	4	{of a plurality of layer connectors}	<administrative transfer to H10W 72/30>
D	H01L24/31	3	{Structure, shape, material or disposition of the layer connectors after the connecting process}	<administrative transfer to H10W 72/30>
D	H01L24/32	4	{of an individual layer connector}	<administrative transfer to H10W 72/30>
D	H01L24/33	4	{of a plurality of layer connectors}	<administrative transfer to H10W 72/30>
D	H01L24/34	2	{Strap connectors, e.g. copper straps for grounding power devices; Manufacturing methods related thereto}	<administrative transfer to H10W 72/60>
D	H01L24/35	3	{Manufacturing methods}	<administrative transfer to H10W 72/016>
D	H01L24/36	3	{Structure, shape, material or disposition of the strap connectors prior to the connecting process}	<administrative transfer to H10W 72/60>
D	H01L24/37	4	{of an individual strap connector}	<administrative transfer to H10W 72/60>
D	H01L24/38	4	{of a plurality of strap connectors}	<administrative transfer to H10W 72/60>
D	H01L24/39	3	{Structure, shape, material or disposition of the strap connectors after the connecting process}	<administrative transfer to H10W 72/60>
D	H01L24/40	4	{of an individual strap connector}	<administrative transfer to H10W 72/60>
D	H01L24/41	4	{of a plurality of strap connectors}	<administrative transfer to H10W 72/60>

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D	H01L24/42	2	{Wire connectors; Manufacturing methods related thereto}	<administrative transfer to H10W 72/50>
D	H01L24/43	3	{Manufacturing methods}	<administrative transfer to H10W 72/015>
D	H01L24/44	3	{Structure, shape, material or disposition of the wire connectors prior to the connecting process}	<administrative transfer to H10W 72/50>
D	H01L24/45	4	{of an individual wire connector}	<administrative transfer to H10W 72/50>
D	H01L24/46	4	{of a plurality of wire connectors}	<administrative transfer to H10W 72/50>
D	H01L24/47	3	{Structure, shape, material or disposition of the wire connectors after the connecting process}	<administrative transfer to H10W 72/50>
D	H01L24/48	4	{of an individual wire connector}	<administrative transfer to H10W 72/50>
D	H01L24/49	4	{of a plurality of wire connectors}	<administrative transfer to H10W 72/50>
D	H01L24/50	2	{Tape automated bonding [TAB] connectors, i.e. film carriers; Manufacturing methods related thereto (thin flexible metallic tape with or without a film carrier H01L23/49572, flexible insulating substrates H01L23/4985, H01L23/5387)}	<administrative transfer to H10W 72/701>
D	H01L24/63	2	{Connectors not provided for in any of the groups H01L24/10 - H01L24/50 and subgroups; Manufacturing methods related thereto}	<administrative transfer to H10W 72/00>

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D	H01L24/64	3	{Manufacturing methods}	<administrative transfer to H10W 72/01>
D	H01L24/65	3	{Structure, shape, material or disposition of the connectors prior to the connecting process}	<administrative transfer to H10W 72/00>
D	H01L24/66	4	{of an individual connector}	<administrative transfer to H10W 72/00>
D	H01L24/67	4	{of a plurality of connectors}	<administrative transfer to H10W 72/00>
D	H01L24/68	3	{Structure, shape, material or disposition of the connectors after the connecting process}	<administrative transfer to H10W 72/00>
D	H01L24/69	4	{of an individual connector}	<administrative transfer to H10W 72/00>
D	H01L24/70	4	{of a plurality of connectors}	<administrative transfer to H10W 72/00>
D	H01L24/71	1	{Means for bonding not being attached to, or not being formed on, the surface to be connected (holders for supporting the complete device in operation H01L23/32)}	<administrative transfer to H10W 72/00>
D	H01L24/72	2	{Detachable connecting means consisting of mechanical auxiliary parts connecting the device, e.g. pressure contacts using springs or clips}	<administrative transfer to H10W 72/00>
D	H01L24/73	1	{Means for bonding being of different types provided for in two or more of groups H01L24/10, H01L24/18, H01L24/26, H01L24/34, H01L24/42, H01L24/50, H01L24/63, H01L24/71}	<administrative transfer to H10W 72/851>

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D	H01L24/74	1	{Apparatus for manufacturing arrangements for connecting or disconnecting semiconductor or solid-state bodies}	<administrative transfer to H10W 72/011>
D	H01L24/741	2	{Apparatus for manufacturing means for bonding, e.g. connectors}	<administrative transfer to H10W 72/011>
D	H01L24/742	3	{Apparatus for manufacturing bump connectors}	<administrative transfer to H10W 72/0112>
D	H01L24/743	3	{Apparatus for manufacturing layer connectors}	<administrative transfer to H10W 72/0113>
D	H01L24/744	3	{Apparatus for manufacturing strap connectors}	<administrative transfer to H10W 72/0116>
D	H01L24/745	3	{Apparatus for manufacturing wire connectors}	<administrative transfer to H10W 72/0115>
D	H01L24/75	2	{Apparatus for connecting with bump connectors or layer connectors}	<administrative transfer to H10W 72/0711>
D	H01L24/76	2	{Apparatus for connecting with build-up interconnects}	<administrative transfer to H10W 72/0711>
D	H01L24/77	2	{Apparatus for connecting with strap connectors}	<administrative transfer to H10W 72/0711>
D	H01L24/78	2	{Apparatus for connecting with wire connectors}	<administrative transfer to H10W 72/0711>
D	H01L24/79	2	{Apparatus for Tape Automated Bonding [TAB]}	<administrative transfer to H10W 72/0711>
D	H01L24/799	2	{Apparatus for disconnecting}	<administrative transfer to H10W 72/0711>
D	H01L24/80	1	{Methods for connecting semiconductor or other solid state bodies using means for bonding being attached to, or being formed on, the surface to be connected}	<administrative transfer to H10W 99/00>
D	H01L24/81	2	{using a bump connector}	<administrative transfer to H10W 72/072>

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D	H01L24/82	2	{by forming build-up interconnects at chip-level, e.g. for high density interconnects [HDI] (interconnection structure between a plurality of semiconductor chips H01L23/5389)}	<administrative transfer to H10W 70/093>
D	H01L24/83	2	{using a layer connector}	<administrative transfer to H10W 72/073>
D	H01L24/84	2	{using a strap connector}	<administrative transfer to H10W 72/076>
D	H01L24/85	2	{using a wire connector (wire bonding in general B23K20/004)}	<administrative transfer to H10W 72/075>
D	H01L24/86	2	{using tape automated bonding [TAB]}	<administrative transfer to H10W 72/077>
D	H01L24/89	2	{using at least one connector not provided for in any of the groups H01L24/81 - H01L24/86}	<administrative transfer to H10W 72/00>
D	H01L24/90	1	{Methods for connecting semiconductor or solid state bodies using means for bonding not being attached to, or not being formed on, the body surface to be connected, e.g. pressure contacts using springs or clips}	<administrative transfer to H10W 72/00>
D	H01L24/91	1	{Methods for connecting semiconductor or solid state bodies including different methods provided for in two or more of groups H01L24/80 - H01L24/90}	<administrative transfer to H10W 99/00>
D	H01L24/92	2	{Specific sequence of method steps}	<administrative transfer to H10W 99/00>
D	H01L24/93	1	{Batch processes}	<administrative transfer to H10W 72/0198>
D	H01L24/94	2	{at wafer-level, i.e. with connecting carried out on a wafer comprising a plurality of undiced individual devices}	<administrative transfer to H10W 72/0198>
D	H01L24/95	2	{at chip-level, i.e. with connecting carried out on a plurality of singulated devices, i.e. on diced chips}	<administrative transfer to H10W 72/0198>

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D	H01L24/96	3	{the devices being encapsulated in a common layer, e.g. neo-wafer or pseudo-wafer, said common layer being separable into individual assemblies after connecting}	<administrative transfer to H10W 72/0198>
D	H01L24/97	3	{the devices being connected to a common substrate, e.g. interposer, said common substrate being separable into individual assemblies after connecting}	<administrative transfer to H10W 72/0198>
D	H01L24/98	1	{Methods for disconnecting semiconductor or solid-state bodies}	<administrative transfer to H10W 72/071>
D	H01L25/00	0	Assemblies consisting of a plurality of semiconductor or other solid state devices (devices consisting of a plurality of solid-state components formed in or on a common substrate H10D89/00; photovoltaic modules or arrays of photovoltaic cells H10F19/00)	<administrative transfer to H10W 90/00>
D	H01L25/03	1	all the devices being of a type provided for in a single subclass of subclasses H10B, H10D, H10F, H10H, H10K or H10N, e.g. assemblies of rectifier diodes	<administrative transfer to H10W 90/00>
D	H01L25/04	2	the devices not having separate containers	<administrative transfer to H10W 90/00>
D	H01L25/041	3	{the devices being of a type provided for in subclass H10F}	<administrative transfer to H10W 90/00>
D	H01L25/042	4	{the devices being arranged next to each other (solar cells H10F19/00)}	<administrative transfer to H10W 90/00>
D	H01L25/043	4	{Stacked arrangements of devices}	<administrative transfer to H10W 90/00>
D	H01L25/065	3	the devices being of a type provided for in group H10D89/00	<administrative transfer to H10W 90/00>

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D	H01L25/0652	4	{the devices being arranged next and on each other, i.e. mixed assemblies}	<administrative transfer to H10W 90/00>
D	H01L25/0655	4	{the devices being arranged next to each other}	<administrative transfer to H10W 90/00>
D	H01L25/0657	4	{Stacked arrangements of devices}	<administrative transfer to H10W 90/00>
D	H01L25/07	3	the devices being of a type provided for in group subclass H10D	<administrative transfer to H10W 90/00>
D	H01L25/071	4	{the devices being arranged next and on each other, i.e. mixed assemblies}	<administrative transfer to H10W 90/00>
D	H01L25/072	4	{the devices being arranged next to each other}	<administrative transfer to H10W 90/00>
D	H01L25/073	4	{Apertured devices mounted on one or more rods passed through the apertures}	<administrative transfer to H10W 90/00>
D	H01L25/074	4	{Stacked arrangements of non-apertured devices}	<administrative transfer to H10W 90/00>
D	H01L25/075	3	the devices being of a type provided for in group H10H20/00	<administrative transfer to H10W 90/00>
D	H01L25/0753	4	{the devices being arranged next to each other}	<administrative transfer to H10W 90/00>
D	H01L25/0756	4	{Stacked arrangements of devices}	<administrative transfer to H10W 90/00>
D	H01L25/10	2	the devices having separate containers	<administrative transfer to H10W 90/00>
D	H01L25/105	3	{the devices being integrated devices of class H10}	<administrative transfer to H10W 90/00>
D	H01L25/11	3	the devices being of a type provided for in subclass H10D	<administrative transfer to H10W 90/00>
D	H01L25/112	4	{Mixed assemblies}	<administrative transfer to H10W 90/00>
D	H01L25/115	4	{the devices being arranged next to each other}	<administrative transfer to H10W 90/00>

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D	H01L25/117	4	{Stacked arrangements of devices}	<administrative transfer to H10W 90/00>
D	H01L25/13	3	the devices being of a type provided for in group H10H20/00	<administrative transfer to H10W 90/00>
D	H01L25/16	1	the devices being of types provided for in two or more different subclasses of H10B, H10D, H10F, H10H, H10K or H10N, e.g. forming hybrid circuits	<administrative transfer to H10W 90/00>
D	H01L25/162	2	{the devices being mounted on two or more different substrates}	<administrative transfer to H10W 90/00>
D	H01L25/165	2	{Containers}	<administrative transfer to H10W 90/00>
D	H01L25/167	2	{comprising optoelectronic devices, e.g. LED, photodiodes}	<administrative transfer to H10W 90/00>
D	H01L25/18	1	the devices being of the types provided for in two or more different main groups of the same subclass of H10B, H10D, H10F, H10H, H10K or H10N	<administrative transfer to H10W 90/00>
D	H01L25/50	1	{Multistep manufacturing processes of assemblies consisting of devices, the devices being individual devices of subclass H10D or integrated devices of class H10 (H01L 21/50 takes precedence)}	<administrative transfer to H10W 90/00>
D	H01L2221/10	1	Applying interconnections to be used for carrying current between separate components within a device	<administrative transfer to H10W 20/01>

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D	H01L2221/1005	2	Formation and after-treatment of dielectrics	<administrative transfer to H10W 20/071>
D	H01L2221/101	3	Forming openings in dielectrics	<administrative transfer to H10W 20/081>
D	H01L2221/1015	4	for dual damascene structures	<administrative transfer to H10W 20/084>
D	H01L2221/1021	5	Pre-forming the dual damascene structure in a resist layer	<administrative transfer to H10W 20/0882>
D	H01L2221/1026	5	the via being formed by burying a sacrificial pillar in the dielectric and removing the pillar	<administrative transfer to H10W 20/0884>
D	H01L2221/1031	5	Dual damascene by forming vias in the via-level dielectric prior to deposition of the trench-level dielectric	<administrative transfer to H10W 20/0886>
D	H01L2221/1036	5	Dual damascene with different via-level and trench-level dielectrics	<administrative transfer to H10W 20/0888>
D	H01L2221/1042	3	the dielectric comprising air gaps	<administrative transfer to H10W 20/072>
D	H01L2221/1047	4	the air gaps being formed by pores in the dielectric	<administrative transfer to H10W 20/072>
D	H01L2221/1052	3	Formation of thin functional dielectric layers	<administrative transfer to H10W 20/074>
D	H01L2221/1057	4	in via holes or trenches	<administrative transfer to H10W 20/076>
D	H01L2221/1063	5	Sacrificial or temporary thin dielectric films in openings in a dielectric	<administrative transfer to H10W 20/0765>
D	H01L2221/1068	2	Formation and after-treatment of conductors	<administrative transfer to H10W 20/031>
D	H01L2221/1073	3	Barrier, adhesion or liner layers	<administrative transfer to H10W 20/032>
D	H01L2221/1078	4	Multiple stacked thin films not being formed in openings in dielectrics	<administrative transfer to H10W 20/0375>
D	H01L2221/1084	4	Layers specifically deposited to enhance or enable the nucleation of further layers, i.e. seed layers	<administrative transfer to H10W 20/042>
D	H01L2221/1089	5	Stacks of seed layers	<administrative transfer to H10W 20/0425>
D	H01L2221/1094	3	Conducting structures comprising nanotubes or nanowires	<administrative transfer to H10W 20/0554>
D	H01L2223/00	0	Details relating to semiconductor or other solid state devices covered by the group H01L23/00	<administrative transfer to H10W 99/00>
D	H01L2223/544	1	Marks applied to semiconductor devices or parts	<administrative transfer to H10W 46/00>
D	H01L2223/54406	2	comprising alphanumeric information	<administrative transfer to H10W 46/103>
D	H01L2223/54413	2	comprising digital information, e.g. bar codes, data matrix	<administrative transfer to H10W 46/106>

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D	H01L2223/5442	2	comprising non digital, non alphanumeric information, e.g. symbols	<administrative transfer to H10W 46/101>
D	H01L2223/54426	2	for alignment	<administrative transfer to H10W 46/301>
D	H01L2223/54433	2	containing identification or tracking information	<administrative transfer to H10W 46/401>
D	H01L2223/5444	3	for electrical read out	<administrative transfer to H10W 46/403>
D	H01L2223/54446	4	Wireless electrical read out	<administrative transfer to H10W 46/407>
D	H01L2223/54453	2	for use prior to dicing	<administrative transfer to H10W 46/501>
D	H01L2223/5446	3	Located in scribe lines	<administrative transfer to H10W 46/503>
D	H01L2223/54466	3	Located in a dummy or reference die	<administrative transfer to H10W 46/507>
D	H01L2223/54473	2	for use after dicing	<administrative transfer to H10W 46/601>
D	H01L2223/5448	3	Located on chip prior to dicing and remaining on chip after dicing	<administrative transfer to H10W 46/603>
D	H01L2223/54486	3	Located on package parts, e.g. encapsulation, leads, package substrate	<administrative transfer to H10W 46/607>
D	H01L2223/54493	2	Peripheral marks on wafers, e.g. orientation flats, notches, lot number	<administrative transfer to H10W 46/201>
D	H01L2223/58	1	Structural electrical arrangements for semiconductor devices not otherwise provided for	<administrative transfer to H10W 42/00>
D	H01L2223/64	2	Impedance arrangements	<administrative transfer to H10W 44/00>
D	H01L2223/66	3	High-frequency adaptations	<administrative transfer to H10W 44/20>
D	H01L2223/6605	4	High-frequency electrical connections	<administrative transfer to H10W 44/203>
D	H01L2223/6611	5	Wire connections	<administrative transfer to H10W 44/206>
D	H01L2223/6616	5	Vertical connections, e.g. vias	<administrative transfer to H10W 44/209>
D	H01L2223/6622	6	Coaxial feed-throughs in active or passive substrates	<administrative transfer to H10W 44/212>
D	H01L2223/6627	5	Waveguides, e.g. microstrip line, strip line, coplanar line	<administrative transfer to H10W 44/216>
D	H01L2223/6633	6	Transition between different waveguide types	<administrative transfer to H10W 44/219>
D	H01L2223/6638	5	Differential pair signal lines	<administrative transfer to H10W 44/223>
D	H01L2223/6644	4	Packaging aspects of high-frequency amplifiers	<administrative transfer to H10W 44/226>

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D	H01L2223/665	5	Bias feed arrangements	<administrative transfer to H10W 44/231>
D	H01L2223/6655	5	Matching arrangements, e.g. arrangement of inductive and capacitive components	<administrative transfer to H10W 44/234>
D	H01L2223/6661	4	for passive devices	<administrative transfer to H10W 44/241>
D	H01L2223/6666	5	for decoupling, e.g. bypass capacitors	<administrative transfer to H10W 44/243>
D	H01L2223/6672	5	for integrated passive components, e.g. semiconductor device with passive components only	<administrative transfer to H10W 44/241>
D	H01L2223/6677	5	for antenna, e.g. antenna included within housing of semiconductor device	<administrative transfer to H10W 44/248>
D	H01L2223/6683	4	for monolithic microwave integrated circuit [MMIC]	<administrative transfer to H10W 44/251>
D	H01L2223/6688	4	Mixed frequency adaptations, i.e. for operation at different frequencies	<administrative transfer to H10W 44/255>
D	H01L2223/6694	4	Optical signal interface included within high-frequency semiconductor device housing	<administrative transfer to H10W 44/259>
D	H01L2224/00	0	Indexing scheme for arrangements for connecting or disconnecting semiconductor or solid-state bodies and methods related thereto as covered by H01L24/00	<administrative transfer to H10W 72/00>
D	H01L2224/01	1	Means for bonding being attached to, or being formed on, the surface to be connected, e.g. chip-to-package, die-attach, "first-level" interconnects; Manufacturing methods related thereto	<administrative transfer to H10W 72/00>
D	H01L2224/02	2	Bonding areas; Manufacturing methods related thereto	<administrative transfer to H10W 72/90>
D	H01L2224/0212	3	Auxiliary members for bonding areas, e.g. spacers	<administrative transfer to H10W 72/981>
D	H01L2224/02122	4	being formed on the semiconductor or solid-state body	<administrative transfer to H10W 72/981>
D	H01L2224/02123	5	inside the bonding area	<administrative transfer to H10W 72/981>
D	H01L2224/02125	6	Reinforcing structures	<administrative transfer to H10W 72/983>
D	H01L2224/02126	7	Collar structures	<administrative transfer to H10W 72/983>
D	H01L2224/0213	6	Alignment aids	<administrative transfer to H10W 72/985>
D	H01L2224/02135	6	Flow barrier	<administrative transfer to H10W 72/987>
D	H01L2224/0214	6	Structure of the auxiliary member	<administrative transfer to H10W 72/981>
D	H01L2224/02141	7	Multilayer auxiliary member	<administrative transfer to H10W 72/981>

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D	H01L2224/02145	6	Shape of the auxiliary member	<administrative transfer to H10W 72/981>
D	H01L2224/0215	6	Material of the auxiliary member	<administrative transfer to H10W 72/981>
D	H01L2224/02163	5	on the bonding area	<administrative transfer to H10W 72/981>
D	H01L2224/02165	6	Reinforcing structures	<administrative transfer to H10W 72/983>
D	H01L2224/02166	7	Collar structures	<administrative transfer to H10W 72/983>
D	H01L2224/0217	6	Alignment aids	<administrative transfer to H10W 72/985>
D	H01L2224/02175	6	Flow barrier	<administrative transfer to H10W 72/987>
D	H01L2224/0218	6	Structure of the auxiliary member	<administrative transfer to H10W 72/981>
D	H01L2224/02181	7	Multilayer auxiliary member	<administrative transfer to H10W 72/981>
D	H01L2224/02185	6	Shape of the auxiliary member	<administrative transfer to H10W 72/981>
D	H01L2224/0219	6	Material of the auxiliary member	<administrative transfer to H10W 72/981>
D	H01L2224/022	6	Protective coating, i.e. protective bond-through coating	<administrative transfer to H10W 72/981>
D	H01L2224/02205	7	Structure of the protective coating	<administrative transfer to H10W 72/981>
D	H01L2224/02206	8	Multilayer protective coating	<administrative transfer to H10W 72/981>
D	H01L2224/0221	7	Shape of the protective coating	<administrative transfer to H10W 72/981>
D	H01L2224/02215	7	Material of the protective coating	<administrative transfer to H10W 72/981>
D	H01L2224/02233	5	not in direct contact with the bonding area	<administrative transfer to H10W 72/981>
D	H01L2224/02235	6	Reinforcing structures	<administrative transfer to H10W 72/983>
D	H01L2224/0224	6	Alignment aids	<administrative transfer to H10W 72/985>
D	H01L2224/02245	6	Flow barrier	<administrative transfer to H10W 72/987>
D	H01L2224/0225	6	Structure of the auxiliary member	<administrative transfer to H10W 72/981>
D	H01L2224/02251	7	Multilayer auxiliary member	<administrative transfer to H10W 72/981>
D	H01L2224/02255	6	Shape of the auxiliary member	<administrative transfer to H10W 72/981>
D	H01L2224/0226	6	Material of the auxiliary member	<administrative transfer to H10W 72/981>

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D	H01L2224/023	3	Redistribution layers [RDL] for bonding areas	<administrative transfer to H10W 70/60>
D	H01L2224/0231	4	Manufacturing methods of the redistribution layers	<administrative transfer to H10W 70/05>
D	H01L2224/02311	5	Additive methods	<administrative transfer to H10W 70/05>
D	H01L2224/02313	5	Subtractive methods	<administrative transfer to H10W 70/05>
D	H01L2224/02315	5	Self-assembly processes	<administrative transfer to H10W 70/05>
D	H01L2224/02317	5	by local deposition	<administrative transfer to H10W 70/05>
D	H01L2224/02319	5	by using a preform	<administrative transfer to H10W 70/05>
D	H01L2224/02321	5	Reworking	<administrative transfer to H10W 70/05>
D	H01L2224/0233	4	Structure of the redistribution layers	<administrative transfer to H10W 70/60>
D	H01L2224/02331	5	Multilayer structure	<administrative transfer to H10W 70/60>
D	H01L2224/02333	5	being a bump	<administrative transfer to H10W 70/60>
D	H01L2224/02335	5	Free-standing redistribution layers	<administrative transfer to H10W 70/60>
D	H01L2224/0235	4	Shape of the redistribution layers	<administrative transfer to H10W 70/65>
D	H01L2224/02351	5	comprising interlocking features	<administrative transfer to H10W 70/65>
D	H01L2224/0236	4	Shape of the insulating layers therebetween	<administrative transfer to H10W 70/68>
D	H01L2224/0237	4	Disposition of the redistribution layers	<administrative transfer to H10W 70/65>
D	H01L2224/02371	5	connecting the bonding area on a surface of the semiconductor or solid-state body with another surface of the semiconductor or solid-state body	<administrative transfer to H10W 70/65>
D	H01L2224/02372	5	connecting to a via connection in the semiconductor or solid-state body	<administrative transfer to H10W 70/65>
D	H01L2224/02373	5	Layout of the redistribution layers	<administrative transfer to H10W 70/65>
D	H01L2224/02375	5	Top view	<administrative transfer to H10W 70/654>
D	H01L2224/02377	5	Fan-in arrangement	<administrative transfer to H10W 70/656>
D	H01L2224/02379	5	Fan-out arrangement	<administrative transfer to H10W 70/655>
D	H01L2224/02381	5	Side view	<administrative transfer to H10W 70/652>

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D	H01L2224/0239	4	Material of the redistribution layers	<administrative transfer to H10W 70/66>
D	H01L2224/024	4	Material of the insulating layers therebetween	<administrative transfer to H10W 70/69>
D	H01L2224/03	3	Manufacturing methods	<administrative transfer to H10W 72/019>
D	H01L2224/03001	4	Involving a temporary auxiliary member not forming part of the manufacturing apparatus, e.g. removable or sacrificial coating, film or substrate	<administrative transfer to H10W 72/01904>
D	H01L2224/03002	5	for supporting the semiconductor or solid-state body	<administrative transfer to H10W 72/01904>
D	H01L2224/03003	5	for holding or transferring a preform	<administrative transfer to H10W 72/01904>
D	H01L2224/03005	5	for aligning the bonding area, e.g. marks, spacers	<administrative transfer to H10W 72/01904>
D	H01L2224/03009	5	for protecting parts during manufacture	<administrative transfer to H10W 72/01904>
D	H01L2224/03011	4	Involving a permanent auxiliary member, i.e. a member which is left at least partly in the finished device, e.g. coating, dummy feature	<administrative transfer to H10W 72/01908>
D	H01L2224/03013	5	for holding or confining the bonding area, e.g. solder flow barrier	<administrative transfer to H10W 72/01908>
D	H01L2224/03015	5	for aligning the bonding area, e.g. marks, spacers	<administrative transfer to H10W 72/01908>
D	H01L2224/03019	5	for protecting parts during the process	<administrative transfer to H10W 72/01908>
D	H01L2224/031	4	Manufacture and pre-treatment of the bonding area preform	<administrative transfer to H10W 72/019>
D	H01L2224/0311	5	Shaping	<administrative transfer to H10W 72/019>
D	H01L2224/0312	5	Applying permanent coating	<administrative transfer to H10W 72/019 and H10W 72/923 simultaneously>
D	H01L2224/033	4	by local deposition of the material of the bonding area	<administrative transfer to H10W 72/01921>
D	H01L2224/0331	5	in liquid form	<administrative transfer to H10W 72/01923>
D	H01L2224/03312	6	Continuous flow, e.g. using a microsyringe, a pump, a nozzle or extrusion	<administrative transfer to H10W 72/01923>
D	H01L2224/03318	6	by dispensing droplets	<administrative transfer to H10W 72/01923>
D	H01L2224/0332	6	Screen printing, i.e. using a stencil	<administrative transfer to H10W 72/01923>
D	H01L2224/0333	5	in solid form	<administrative transfer to H10W 72/01925>

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D	H01L2224/03332	6	using a powder	<administrative transfer to H10W 72/01925>
D	H01L2224/03334	6	using a preform	<administrative transfer to H10W 72/01925>
D	H01L2224/034	4	by blanket deposition of the material of the bonding area	<administrative transfer to H10W 72/01931>
D	H01L2224/0341	5	in liquid form	<administrative transfer to H10W 72/01933>
D	H01L2224/03416	6	Spin coating	<administrative transfer to H10W 72/01933>
D	H01L2224/03418	6	Spray coating	<administrative transfer to H10W 72/01933>
D	H01L2224/0342	6	Curtain coating	<administrative transfer to H10W 72/01933>
D	H01L2224/03422	6	by dipping, e.g. in a solder bath	<administrative transfer to H10W 72/01933>
D	H01L2224/03424	6	Immersion coating, e.g. in a solder bath	<administrative transfer to H10W 72/01933>
D	H01L2224/03426	6	Chemical solution deposition [CSD], i.e. using a liquid precursor	<administrative transfer to H10W 72/01933>
D	H01L2224/03428	6	Wave coating	<administrative transfer to H10W 72/01933>
D	H01L2224/0343	5	in solid form	<administrative transfer to H10W 72/01936>
D	H01L2224/03436	6	Lamination of a preform, e.g. foil, sheet or layer	<administrative transfer to H10W 72/01936>
D	H01L2224/03438	7	the preform being at least partly pre-patterned	<administrative transfer to H10W 72/01936>
D	H01L2224/0344	7	by transfer printing	<administrative transfer to H10W 72/01936>
D	H01L2224/03442	6	using a powder	<administrative transfer to H10W 72/01936>
D	H01L2224/03444	5	in gaseous form	<administrative transfer to H10W 72/01938>
D	H01L2224/0345	6	Physical vapour deposition [PVD], e.g. evaporation, or sputtering	<administrative transfer to H10W 72/01938>
D	H01L2224/03452	6	Chemical vapour deposition [CVD], e.g. laser CVD	<administrative transfer to H10W 72/01938>
D	H01L2224/0346	5	Plating	<administrative transfer to H10W 72/01935>
D	H01L2224/03462	6	Electroplating	<administrative transfer to H10W 72/01935>
D	H01L2224/03464	6	Electroless plating	<administrative transfer to H10W 72/01935>
D	H01L2224/03466	5	Conformal deposition, i.e. blanket deposition of a conformal layer on a patterned surface	<administrative transfer to H10W 72/01931>
D	H01L2224/0347	4	using a lift-off mask	<administrative transfer to H10W 72/01955>

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D	H01L2224/03472	5	Profile of the lift-off mask	<administrative transfer to H10W 72/01955>
D	H01L2224/03474	5	Multilayer masks	<administrative transfer to H10W 72/01955>
D	H01L2224/0348	5	Permanent masks, i.e. masks left in the finished device, e.g. passivation layers	<administrative transfer to H10W 72/01955>
D	H01L2224/035	4	by chemical or physical modification of a pre-existing or pre-deposited material	<administrative transfer to H10W 72/01961>
D	H01L2224/03502	5	Pre-existing or pre-deposited material	<administrative transfer to H10W 72/01961>
D	H01L2224/03505	5	Sintering	<administrative transfer to H10W 72/01961>
D	H01L2224/0351	5	Anodisation	<administrative transfer to H10W 72/01961>
D	H01L2224/03515	5	Curing and solidification, e.g. of a photosensitive material	<administrative transfer to H10W 72/01961>
D	H01L2224/0352	5	Self-assembly, e.g. self-agglomeration of the material in a fluid	<administrative transfer to H10W 72/01961>
D	H01L2224/03522	6	Auxiliary means therefor, e.g. for self-assembly activation	<administrative transfer to H10W 72/01961>
D	H01L2224/03524	6	with special adaptation of the surface of the body to be connected or of an auxiliary substrate, e.g. surface shape specially adapted for the self-assembly process	<administrative transfer to H10W 72/01961>
D	H01L2224/0355	5	Selective modification	<administrative transfer to H10W 72/01961>
D	H01L2224/03552	6	using a laser or a focussed ion beam [FIB]	<administrative transfer to H10W 72/01961>
D	H01L2224/03554	7	Stereolithography, i.e. solidification of a pattern defined by a laser trace in a photosensitive resin	<administrative transfer to H10W 72/01961>
D	H01L2224/036	4	by patterning a pre-deposited material	<administrative transfer to H10W 72/01951>
D	H01L2224/03602	5	Mechanical treatment, e.g. polishing, grinding	<administrative transfer to H10W 72/01951>
D	H01L2224/0361	5	Physical or chemical etching	<administrative transfer to H10W 72/01953>
D	H01L2224/03612	6	by physical means only	<administrative transfer to H10W 72/01953>
D	H01L2224/03614	6	by chemical means only	<administrative transfer to H10W 72/01953>
D	H01L2224/03616	6	Chemical mechanical polishing [CMP]	<administrative transfer to H10W 72/01953>
D	H01L2224/03618	5	with selective exposure, development and removal of a photosensitive material, e.g. of a photosensitive conductive resin	<administrative transfer to H10W 72/01951>
D	H01L2224/0362	6	Photolithography	<administrative transfer to H10W 72/01951>

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D	H01L2224/03622	5	using masks	<administrative transfer to H10W 72/01951>
D	H01L2224/0363	5	using a laser or a focused ion beam [FIB]	<administrative transfer to H10W 72/01951>
D	H01L2224/03632	6	Ablation by means of a laser or focused ion beam [FIB]	<administrative transfer to H10W 72/01951>
D	H01L2224/037	4	involving monitoring, e.g. feedback loop	<administrative transfer to H10W 72/019>
D	H01L2224/038	4	Post-treatment of the bonding area	<administrative transfer to H10W 72/019>
D	H01L2224/0381	5	Cleaning, e.g. oxide removal step, desmearing	<administrative transfer to H10W 72/01971>
D	H01L2224/0382	5	Applying permanent coating, e.g. in-situ coating	<administrative transfer to H10W 72/019 and H10W 72/923 simultaneously>
D	H01L2224/03821	6	Spray coating	<administrative transfer to H10W 72/019 and H10W 72/923 simultaneously>
D	H01L2224/03822	6	by dipping, e.g. in a solder bath	<administrative transfer to H10W 72/019 and H10W 72/923 simultaneously>
D	H01L2224/03823	6	Immersion coating, e.g. in a solder bath	<administrative transfer to H10W 72/019 and H10W 72/923 simultaneously>
D	H01L2224/03824	6	Chemical solution deposition [CSD], i.e. using a liquid precursor	<administrative transfer to H10W 72/019 and H10W 72/923 simultaneously>
D	H01L2224/03825	6	Plating, e.g. electroplating, electroless plating	<administrative transfer to H10W 72/019 and H10W 72/923 simultaneously>
D	H01L2224/03826	6	Physical vapour deposition [PVD], e.g. evaporation, or sputtering	<administrative transfer to H10W 72/019 and H10W 72/923 simultaneously>
D	H01L2224/03827	6	Chemical vapour deposition [CVD], e.g. laser CVD	<administrative transfer to H10W 72/019 and H10W 72/923 simultaneously>
D	H01L2224/03828	5	Applying flux	<administrative transfer to H10W 72/019>
D	H01L2224/03829	5	Applying a precursor material	<administrative transfer to H10W 72/019>

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D	H01L2224/0383	5	Reworking, e.g. shaping	<administrative transfer to H10W 72/01951>
D	H01L2224/03831	6	involving a chemical process, e.g. etching the bonding area	<administrative transfer to H10W 72/01953>
D	H01L2224/0384	6	involving a mechanical process, e.g. planarising the bonding area	<administrative transfer to H10W 72/01951>
D	H01L2224/03845	6	Chemical mechanical polishing [CMP]	<administrative transfer to H10W 72/01951>
D	H01L2224/03848	5	Thermal treatments, e.g. annealing, controlled cooling	<administrative transfer to H10W 72/019>
D	H01L2224/03849	6	Reflowing	<administrative transfer to H10W 72/01951>
D	H01L2224/039	4	Methods of manufacturing bonding areas involving a specific sequence of method steps	<administrative transfer to H10W 72/019>
D	H01L2224/03901	5	with repetition of the same manufacturing step	<administrative transfer to H10W 72/019>
D	H01L2224/03902	6	Multiple masking steps	<administrative transfer to H10W 72/019>
D	H01L2224/03903	7	using different masks	<administrative transfer to H10W 72/019>
D	H01L2224/03906	7	with modification of the same mask	<administrative transfer to H10W 72/019>
D	H01L2224/0391	5	Forming a passivation layer after forming the bonding area	<administrative transfer to H10W 72/019>
D	H01L2224/03912	5	the bump being used as a mask for patterning the bonding area	<administrative transfer to H10W 72/019>
D	H01L2224/03914	5	the bonding area, e.g. under bump metallisation [UBM], being used as a mask for patterning other parts	<administrative transfer to H10W 72/019>
D	H01L2224/03916	5	a passivation layer being used as a mask for patterning the bonding area	<administrative transfer to H10W 72/019>
D	H01L2224/0392	5	specifically adapted to include a probing step	<administrative transfer to H10W 72/019>
D	H01L2224/03921	6	by repairing the bonding area damaged by the probing step	<administrative transfer to H10W 72/019>
D	H01L2224/04	3	Structure, shape, material or disposition of the bonding areas prior to the connecting process	<administrative transfer to H10W 72/90>
D	H01L2224/0401	4	Bonding areas specifically adapted for bump connectors, e.g. under bump metallisation [UBM]	<administrative transfer to H10W 72/29>
D	H01L2224/04026	4	Bonding areas specifically adapted for layer connectors	<administrative transfer to H10W 72/59>
D	H01L2224/04034	4	Bonding areas specifically adapted for strap connectors	<administrative transfer to H10W 72/691>
D	H01L2224/04042	4	Bonding areas specifically adapted for wire connectors, e.g. wirebond pads	<administrative transfer to H10W 72/59>

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D	H01L2224/0405	4	Bonding areas specifically adapted for tape automated bonding [TAB] connectors	<administrative transfer to H10W 72/709>
D	H01L2224/04073	4	Bonding areas specifically adapted for connectors of different types	<administrative transfer to H10W 72/90>
D	H01L2224/04105	4	Bonding areas formed on an encapsulation of the semiconductor or solid-state body, e.g. bonding areas on chip-scale packages	<administrative transfer to H10W 72/9413>
D	H01L2224/05	4	of an individual bonding area	<administrative transfer to H10W 72/90>
D	H01L2224/05001	5	Internal layers	<administrative transfer to H10W 72/923>
D	H01L2224/05005	6	Structure	<administrative transfer to H10W 72/923 and H10W 72/921 simultaneously>
D	H01L2224/05006	7	Dual damascene structure	<administrative transfer to H10W 72/923 and H10W 72/921 simultaneously>
D	H01L2224/05007	7	comprising a core and a coating	<administrative transfer to H10W 72/923>
D	H01L2224/05008	7	Bonding area integrally formed with a redistribution layer on the semiconductor or solid-state body, e.g.	<administrative transfer to H10W 72/923 and H10W 72/9223 simultaneously>
D	H01L2224/05009	7	Bonding area integrally formed with a via connection of the semiconductor or solid-state body	<administrative transfer to H10W 72/923 and H10W 72/9226 simultaneously>
D	H01L2224/0501	6	Shape	<administrative transfer to H10W 72/923 and H10W 72/931 simultaneously>
D	H01L2224/05011	7	comprising apertures or cavities	<administrative transfer to H10W 72/923>
D	H01L2224/05012	7	in top view	<administrative transfer to H10W 72/923 and H10W 72/932 simultaneously>
D	H01L2224/05013	8	being rectangular	<administrative transfer to H10W 72/923 and H10W 72/932 simultaneously>
D	H01L2224/05014	8	being square	<administrative transfer to H10W 72/923 and H10W 72/932 simultaneously>
D	H01L2224/05015	8	being circular or elliptic	<administrative transfer to H10W 72/923 and

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				H10W 72/932 simultaneously>
D	H01L2224/05016	7	in side view	<administrative transfer to H10W 72/923 and H10W 72/934 simultaneously>
D	H01L2224/05017	8	comprising protrusions or indentations	<administrative transfer to H10W 72/923 and H10W 72/934 simultaneously>
D	H01L2224/05018	8	being a conformal layer on a patterned surface	<administrative transfer to H10W 72/923 and H10W 72/934 simultaneously>
D	H01L2224/05019	8	being a non conformal layer on a patterned surface	<administrative transfer to H10W 72/923 and H10W 72/934 simultaneously>
D	H01L2224/0502	6	Disposition	<administrative transfer to H10W 72/923 and H10W 72/941 simultaneously>
D	H01L2224/05022	7	the internal layer being at least partially embedded in the surface	<administrative transfer to H10W 72/923 and H10W 72/9415 simultaneously>
D	H01L2224/05023	7	the whole internal layer protruding from the surface	<administrative transfer to H10W 72/923 and H10W 72/9415 simultaneously>
D	H01L2224/05024	7	the internal layer being disposed on a redistribution layer on the semiconductor or solid-state body	<administrative transfer to H10W 72/923 and H10W 72/942 simultaneously>
D	H01L2224/05025	7	the internal layer being disposed on a via connection of the semiconductor or solid- state body	<administrative transfer to H10W 72/923 and H10W 72/942 simultaneously>
D	H01L2224/05026	7	the internal layer being disposed in a recess of the surface	<administrative transfer to H10W 72/923 and H10W 72/9415 simultaneously>
D	H01L2224/05027	8	the internal layer extending out of an opening	<administrative transfer to H10W 72/923 and H10W 72/9415 simultaneously>
D	H01L2224/05073	6	Single internal layer	<administrative transfer to H10W 72/923>
D	H01L2224/05075	6	Plural internal layers	<administrative transfer to H10W 72/923>

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D	H01L2224/05076	7	being mutually engaged together, e.g. through inserts	<administrative transfer to H10W 72/923 and H10W 72/921 simultaneously>
D	H01L2224/05078	7	being disposed next to each other, e.g. side-to-side arrangements	<administrative transfer to H10W 72/923 and H10W 72/924 simultaneously>
D	H01L2224/0508	7	being stacked	<administrative transfer to H10W 72/923>
D	H01L2224/05082	8	Two-layer arrangements	<administrative transfer to H10W 72/923>
D	H01L2224/05083	8	Three-layer arrangements	<administrative transfer to H10W 72/923>
D	H01L2224/05084	8	Four-layer arrangements	<administrative transfer to H10W 72/923>
D	H01L2224/05085	8	with additional elements, e.g. vias arrays, interposed between the stacked layers	<administrative transfer to H10W 72/923 and H10W 72/9232 simultaneously>
D	H01L2224/05086	9	Structure of the additional element	<administrative transfer to H10W 72/9232>
D	H01L2224/05087	10	being a via with at least a lining layer	<administrative transfer to H10W 72/9232>
D	H01L2224/05088	9	Shape of the additional element	<administrative transfer to H10W 72/9232>
D	H01L2224/05089	9	Disposition of the additional element	<administrative transfer to H10W 72/9232>
D	H01L2224/0509	10	of a single via	<administrative transfer to H10W 72/9232>
D	H01L2224/05091	11	at the center of the internal layers	<administrative transfer to H10W 72/9232>
D	H01L2224/05092	11	at the periphery of the internal layers	<administrative transfer to H10W 72/9232>
D	H01L2224/05093	10	of a plurality of vias	<administrative transfer to H10W 72/9232>
D	H01L2224/05094	11	at the center of the internal layers	<administrative transfer to H10W 72/9232>
D	H01L2224/05095	11	at the periphery of the internal layers	<administrative transfer to H10W 72/9232>
D	H01L2224/05096	11	Uniform arrangement, i.e. array	<administrative transfer to H10W 72/9232>
D	H01L2224/05097	11	Random arrangement	<administrative transfer to H10W 72/9232>
D	H01L2224/05098	9	Material of the additional element	<administrative transfer to H10W 72/923 and H10W 72/9232 simultaneously>

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D	H01L2224/05099	6	Material	<administrative transfer to H10W 72/923 and H10W 72/951 simultaneously>
D	H01L2224/051	7	with a principal constituent of the material being a metal or a metalloid, e.g. boron [B], silicon [Si], germanium [Ge], arsenic [As], antimony [Sb], tellurium [Te] and polonium [Po], and alloys thereof	<administrative transfer to H10W 72/923 and H10W 72/952 simultaneously>
D	H01L2224/05101	8	the principal constituent melting at a temperature of less than 400°C	<administrative transfer to H10W 72/923 and H10W 72/952 simultaneously>
D	H01L2224/05105	9	Gallium [Ga] as principal constituent	<administrative transfer to H10W 72/923 and H10W 72/952 simultaneously>
D	H01L2224/05109	9	Indium [In] as principal constituent	<administrative transfer to H10W 72/923 and H10W 72/952 simultaneously>
D	H01L2224/05111	9	Tin [Sn] as principal constituent	<administrative transfer to H10W 72/923 and H10W 72/952 simultaneously>
D	H01L2224/05113	9	Bismuth [Bi] as principal constituent	<administrative transfer to H10W 72/923 and H10W 72/952 simultaneously>
D	H01L2224/05114	9	Thallium [Tl] as principal constituent	<administrative transfer to H10W 72/923 and H10W 72/952 simultaneously>
D	H01L2224/05116	9	Lead [Pb] as principal constituent	<administrative transfer to H10W 72/923 and H10W 72/952 simultaneously>
D	H01L2224/05117	8	the principal constituent melting at a temperature of greater than or equal to 400°C and less than 950°C	<administrative transfer to H10W 72/923 and H10W 72/952 simultaneously>
D	H01L2224/05118	9	Zinc [Zn] as principal constituent	<administrative transfer to H10W 72/923 and H10W 72/952 simultaneously>
D	H01L2224/0512	9	Antimony [Sb] as principal constituent	<administrative transfer to H10W 72/923 and H10W 72/952 simultaneously>

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D	H01L2224/05123	9	Magnesium [Mg] as principal constituent	<administrative transfer to H10W 72/923 and H10W 72/952 simultaneously>
D	H01L2224/05124	9	Aluminium [Al] as principal constituent	<administrative transfer to H10W 72/923 and H10W 72/952 simultaneously>
D	H01L2224/05138	8	the principal constituent melting at a temperature of greater than or equal to 950°C and less than 1550°C	<administrative transfer to H10W 72/923 and H10W 72/952 simultaneously>
D	H01L2224/05139	9	Silver [Ag] as principal constituent	<administrative transfer to H10W 72/923 and H10W 72/952 simultaneously>
D	H01L2224/05144	9	Gold [Au] as principal constituent	<administrative transfer to H10W 72/923 and H10W 72/952 simultaneously>
D	H01L2224/05147	9	Copper [Cu] as principal constituent	<administrative transfer to H10W 72/923 and H10W 72/952 simultaneously>
D	H01L2224/05149	9	Manganese [Mn] as principal constituent	<administrative transfer to H10W 72/923 and H10W 72/952 simultaneously>
D	H01L2224/05155	9	Nickel [Ni] as principal constituent	<administrative transfer to H10W 72/923 and H10W 72/952 simultaneously>
D	H01L2224/05157	9	Cobalt [Co] as principal constituent	<administrative transfer to H10W 72/923 and H10W 72/952 simultaneously>
D	H01L2224/0516	9	Iron [Fe] as principal constituent	<administrative transfer to H10W 72/923 and H10W 72/952 simultaneously>
D	H01L2224/05163	8	the principal constituent melting at a temperature of greater than 1550°C	<administrative transfer to H10W 72/923 and H10W 72/952 simultaneously>
D	H01L2224/05164	9	Palladium [Pd] as principal constituent	<administrative transfer to H10W 72/923 and H10W 72/952 simultaneously>
D	H01L2224/05166	9	Titanium [Ti] as principal constituent	<administrative transfer to H10W 72/923 and

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				H10W 72/952 simultaneously>
D	H01L2224/05169	9	Platinum [Pt] as principal constituent	<administrative transfer to H10W 72/923 and H10W 72/952 simultaneously>
D	H01L2224/0517	9	Zirconium [Zr] as principal constituent	<administrative transfer to H10W 72/923 and H10W 72/952 simultaneously>
D	H01L2224/05171	9	Chromium [Cr] as principal constituent	<administrative transfer to H10W 72/923 and H10W 72/952 simultaneously>
D	H01L2224/05172	9	Vanadium [V] as principal constituent	<administrative transfer to H10W 72/923 and H10W 72/952 simultaneously>
D	H01L2224/05173	9	Rhodium [Rh] as principal constituent	<administrative transfer to H10W 72/923 and H10W 72/952 simultaneously>
D	H01L2224/05176	9	Ruthenium [Ru] as principal constituent	<administrative transfer to H10W 72/923 and H10W 72/952 simultaneously>
D	H01L2224/05178	9	Iridium [Ir] as principal constituent	<administrative transfer to H10W 72/923 and H10W 72/952 simultaneously>
D	H01L2224/05179	9	Niobium [Nb] as principal constituent	<administrative transfer to H10W 72/923 and H10W 72/952 simultaneously>
D	H01L2224/0518	9	Molybdenum [Mo] as principal constituent	<administrative transfer to H10W 72/923 and H10W 72/952 simultaneously>
D	H01L2224/05181	9	Tantalum [Ta] as principal constituent	<administrative transfer to H10W 72/923 and H10W 72/952 simultaneously>
D	H01L2224/05183	9	Rhenium [Re] as principal constituent	<administrative transfer to H10W 72/923 and H10W 72/952 simultaneously>
D	H01L2224/05184	9	Tungsten [W] as principal constituent	<administrative transfer to H10W 72/923 and H10W 72/952 simultaneously>

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D	H01L2224/05186	7	with a principal constituent of the material being a non metallic, non metalloid inorganic material	<administrative transfer to H10W 72/923 and H10W 72/952 simultaneously>
D	H01L2224/05187	8	Ceramics, e.g. crystalline carbides, nitrides or oxides	<administrative transfer to H10W 72/923 and H10W 72/952 simultaneously>
D	H01L2224/05188	8	Glasses, e.g. amorphous oxides, nitrides or fluorides	<administrative transfer to H10W 72/923 and H10W 72/952 simultaneously>
D	H01L2224/0519	7	with a principal constituent of the material being a polymer, e.g. polyester, phenolic based polymer, epoxy	<administrative transfer to H10W 72/923 and H10W 72/952 simultaneously>
D	H01L2224/05191	8	The principal constituent being an elastomer, e.g. silicones, isoprene, neoprene	<administrative transfer to H10W 72/923 and H10W 72/953 simultaneously>
D	H01L2224/05193	7	with a principal constituent of the material being a solid not provided for in groups H01L2224/051 - H01L2224/05191, e.g. allotropes of carbon, fullerene, graphite, carbon-nanotubes, diamond	<administrative transfer to H10W 72/923 and H10W 72/953 simultaneously>
D	H01L2224/05194	7	with a principal constituent of the material being a liquid not provided for in groups H01L2224/051 - H01L2224/05191	<administrative transfer to H10W 72/923 and H10W 72/953 simultaneously>
D	H01L2224/05195	7	with a principal constituent of the material being a gas not provided for in groups H01L2224/051 - H01L2224/05191	<administrative transfer to H10W 72/923 and H10W 72/953 simultaneously>
D	H01L2224/05198	7	with a principal constituent of the material being a combination of two or more materials in the form of a matrix with a filler, i.e. being a hybrid material, e.g. segmented structures, foams	<administrative transfer to H10W 72/923 and H10W 72/925 simultaneously>
D	H01L2224/05199	8	Material of the matrix	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/951 simultaneously>
D	H01L2224/052	9	with a principal constituent of the material being a metal or a metalloid, e.g. boron [B], silicon [Si], germanium [Ge], arsenic [As], antimony [Sb], tellurium [Te] and polonium [Po], and alloys thereof	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05201	10	the principal constituent melting at a temperature of less than 400°C	<administrative transfer to H10W 72/923, H10W

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				72/925 and H10W 72/952 simultaneously>
D	H01L2224/05205	11	Gallium [Ga] as principal constituent	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05209	11	Indium [In] as principal constituent	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05211	11	Tin [Sn] as principal constituent	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05213	11	Bismuth [Bi] as principal constituent	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05214	11	Thallium [Tl] as principal constituent	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05216	11	Lead [Pb] as principal constituent	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05217	10	the principal constituent melting at a temperature of greater than or equal to 400°C and less than 950°C	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05218	11	Zinc [Zn] as principal constituent	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/0522	11	Antimony [Sb] as principal constituent	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05223	11	Magnesium [Mg] as principal constituent	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05224	11	Aluminium [Al] as principal constituent	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05238	10	the principal constituent melting at a temperature of greater than or equal to 950°C and less than 1550°C	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>

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D	H01L2224/05239	11	Silver [Ag] as principal constituent	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05244	11	Gold [Au] as principal constituent	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05247	11	Copper [Cu] as principal constituent	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05249	11	Manganese [Mn] as principal constituent	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05255	11	Nickel [Ni] as principal constituent	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05257	11	Cobalt [Co] as principal constituent	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/0526	11	Iron [Fe] as principal constituent	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05263	10	the principal constituent melting at a temperature of greater than 1550°C	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05264	11	Palladium [Pd] as principal constituent	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05266	11	Titanium [Ti] as principal constituent	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05269	11	Platinum [Pt] as principal constituent	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/0527	11	Zirconium [Zr] as principal constituent	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05271	11	Chromium [Cr] as principal constituent	<administrative transfer to H10W 72/923, H10W

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				72/925 and H10W 72/952 simultaneously>
D	H01L2224/05272	11	Vanadium [V] as principal constituent	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05273	11	Rhodium [Rh] as principal constituent	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05276	11	Ruthenium [Ru] as principal constituent	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05278	11	Iridium [Ir] as principal constituent	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05279	11	Niobium [Nb] as principal constituent	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/0528	11	Molybdenum [Mo] as principal constituent	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05281	11	Tantalum [Ta] as principal constituent	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05283	11	Rhenium [Re] as principal constituent	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05284	11	Tungsten [W] as principal constituent	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05286	9	with a principal constituent of the material being a non metallic, non metalloid inorganic material	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/953 simultaneously>
D	H01L2224/05287	10	Ceramics, e.g. crystalline carbides, nitrides or oxides	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/953 simultaneously>
D	H01L2224/05288	10	Glasses, e.g. amorphous oxides, nitrides or fluorides	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/953 simultaneously>

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D	H01L2224/0529	9	with a principal constituent of the material being a polymer, e.g. polyester, phenolic based polymer, epoxy	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/953 simultaneously>
D	H01L2224/05291	10	The principal constituent being an elastomer, e.g. silicones, isoprene, neoprene	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/953 simultaneously>
D	H01L2224/05293	9	with a principal constituent of the material being a solid not provided for in groups H01L2224/052 - H01L2224/05291, e.g. allotropes of carbon, fullerene, graphite, carbon-nanotubes, diamond	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/953 simultaneously>
D	H01L2224/05294	9	with a principal constituent of the material being a liquid not provided for in groups H01L2224/052 - H01L2224/05291	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/953 simultaneously>
D	H01L2224/05295	9	with a principal constituent of the material being a gas not provided for in groups H01L2224/052 - H01L2224/05291	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/953 simultaneously>
D	H01L2224/05298	8	Fillers	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/951 simultaneously>
D	H01L2224/05299	9	Base material	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/951 simultaneously>
D	H01L2224/053	10	with a principal constituent of the material being a metal or a metalloid, e.g. boron [B], silicon [Si], germanium [Ge], arsenic [As], antimony [Sb], tellurium [Te] and polonium [Po], and alloys thereof	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05301	11	the principal constituent melting at a temperature of less than 400°C	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05305	12	Gallium [Ga] as principal constituent	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05309	12	Indium [In] as principal constituent	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05311	12	Tin [Sn] as principal constituent	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>

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D	H01L2224/05313	12	Bismuth [Bi] as principal constituent	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05314	12	Thallium [Tl] as principal constituent	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05316	12	Lead [Pb] as principal constituent	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05317	11	the principal constituent melting at a temperature of greater than or equal to 400°C and less than 950°C	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05318	12	Zinc [Zn] as principal constituent	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/0532	12	Antimony [Sb] as principal constituent	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05323	12	Magnesium [Mg] as principal constituent	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05324	12	Aluminium [Al] as principal constituent	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05338	11	the principal constituent melting at a temperature of greater than or equal to 950°C and less than 1550°C	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05339	12	Silver [Ag] as principal constituent	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05344	12	Gold [Au] as principal constituent	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05347	12	Copper [Cu] as principal constituent	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05349	12	Manganese [Mn] as principal constituent	<administrative transfer to H10W 72/923, H10W

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				72/925 and H10W 72/952 simultaneously>
D	H01L2224/05355	12	Nickel [Ni] as principal constituent	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05357	12	Cobalt [Co] as principal constituent	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/0536	12	Iron [Fe] as principal constituent	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05363	11	the principal constituent melting at a temperature of greater than 1550°C	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05364	12	Palladium [Pd] as principal constituent	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05366	12	Titanium [Ti] as principal constituent	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05369	12	Platinum [Pt] as principal constituent	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/0537	12	Zirconium [Zr] as principal constituent	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05371	12	Chromium [Cr] as principal constituent	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05372	12	Vanadium [V] as principal constituent	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05373	12	Rhodium [Rh] as principal constituent	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05376	12	Ruthenium [Ru] as principal constituent	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>

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D	H01L2224/05378	12	Iridium [Ir] as principal constituent	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05379	12	Niobium [Nb] as principal constituent	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/0538	12	Molybdenum [Mo] as principal constituent	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05381	12	Tantalum [Ta] as principal constituent	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05383	12	Rhenium [Re] as principal constituent	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05384	12	Tungsten [W] as principal constituent	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05386	10	with a principal constituent of the material being a non metallic, non metalloid inorganic material	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/953 simultaneously>
D	H01L2224/05387	11	Ceramics, e.g. crystalline carbides, nitrides or oxides	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/953 simultaneously>
D	H01L2224/05388	11	Glasses, e.g. amorphous oxides, nitrides or fluorides	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/953 simultaneously>
D	H01L2224/0539	10	with a principal constituent of the material being a polymer, e.g. polyester, phenolic based polymer, epoxy	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/953 simultaneously>
D	H01L2224/05391	11	The principal constituent being an elastomer, e.g. silicones, isoprene, neoprene	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/953 simultaneously>
D	H01L2224/05393	10	with a principal constituent of the material being a solid not provided for in groups H01L2224/053 - H01L2224/05391, e.g. allotropes of carbon, fullerene, graphite, carbon-nanotubes, diamond	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/953 simultaneously>

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D	H01L2224/05394	10	with a principal constituent of the material being a liquid not provided for in groups H01L2224/053 - H01L2224/05391	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/953 simultaneously>
D	H01L2224/05395	10	with a principal constituent of the material being a gas not provided for in groups H01L2224/053 - H01L2224/05391	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/953 simultaneously>
D	H01L2224/05398	10	with a principal constituent of the material being a combination of two or more materials in the form of a matrix with a filler, i.e. being a hybrid material, e.g. segmented structures, foams	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/953 simultaneously>
D	H01L2224/05399	9	Coating material	<administrative transfer to H10W 72/923 and H10W 72/925 simultaneously>
D	H01L2224/054	10	with a principal constituent of the material being a metal or a metalloid, e.g. boron [B], silicon [Si], germanium [Ge], arsenic [As], antimony [Sb], tellurium [Te] and polonium [Po], and alloys thereof	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05401	11	the principal constituent melting at a temperature of less than 400°C	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05405	12	Gallium [Ga] as principal constituent	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05409	12	Indium [In] as principal constituent	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05411	12	Tin [Sn] as principal constituent	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05413	12	Bismuth [Bi] as principal constituent	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05414	12	Thallium [Tl] as principal constituent	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05416	12	Lead [Pb] as principal constituent	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>

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D	H01L2224/05417	11	the principal constituent melting at a temperature of greater than or equal to 400°C and less than 950°C	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05418	12	Zinc [Zn] as principal constituent	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/0542	12	Antimony [Sb] as principal constituent	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05423	12	Magnesium [Mg] as principal constituent	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05424	12	Aluminium [Al] as principal constituent	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05438	11	the principal constituent melting at a temperature of greater than or equal to 950°C and less than 1550°C	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05439	12	Silver [Ag] as principal constituent	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05444	12	Gold [Au] as principal constituent	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05447	12	Copper [Cu] as principal constituent	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05449	12	Manganese [Mn] as principal constituent	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05455	12	Nickel [Ni] as principal constituent	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05457	12	Cobalt [Co] as principal constituent	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/0546	12	Iron [Fe] as principal constituent	<administrative transfer to H10W 72/923, H10W

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				72/925 and H10W 72/952 simultaneously>
D	H01L2224/05463	11	the principal constituent melting at a temperature of greater than 1550°C	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05464	12	Palladium [Pd] as principal constituent	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05466	12	Titanium [Ti] as principal constituent	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05469	12	Platinum [Pt] as principal constituent	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/0547	12	Zirconium [Zr] as principal constituent	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05471	12	Chromium [Cr] as principal constituent	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05472	12	Vanadium [V] as principal constituent	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05473	12	Rhodium [Rh] as principal constituent	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05476	12	Ruthenium [Ru] as principal constituent	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05478	12	Iridium [Ir] as principal constituent	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05479	12	Niobium [Nb] as principal constituent	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/0548	12	Molybdenum [Mo] as principal constituent	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>

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D	H01L2224/05481	12	Tantalum [Ta] as principal constituent	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05483	12	Rhenium [Re] as principal constituent	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05484	12	Tungsten [W] as principal constituent	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05486	10	with a principal constituent of the material being a non metallic, non metalloid inorganic material	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/953 simultaneously>
D	H01L2224/05487	11	Ceramics, e.g. crystalline carbides, nitrides or oxides	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/953 simultaneously>
D	H01L2224/05488	11	Glasses, e.g. amorphous oxides, nitrides or fluorides	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/953 simultaneously>
D	H01L2224/0549	10	with a principal constituent of the material being a polymer, e.g. polyester, phenolic based polymer, epoxy	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/953 simultaneously>
D	H01L2224/05491	11	The principal constituent being an elastomer, e.g. silicones, isoprene, neoprene	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/953 simultaneously>
D	H01L2224/05493	10	with a principal constituent of the material being a solid not provided for in groups H01L2224/054 - H01L2224/05491, e.g. allotropes of carbon, fullerene, graphite, carbon-nanotubes, diamond	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/953 simultaneously>
D	H01L2224/05494	10	with a principal constituent of the material being a liquid not provided for in groups H01L2224/054 - H01L2224/05491	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/953 simultaneously>
D	H01L2224/05495	10	with a principal constituent of the material being a gas not provided for in groups H01L2224/054 - H01L2224/05491	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/953 simultaneously>
D	H01L2224/05498	10	with a principal constituent of the material being a combination of two or more materials in the form of a matrix with a filler, i.e. being a hybrid material, e.g. segmented structures, foams	<administrative transfer to H10W 72/923 and H10W 72/925 simultaneously>

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D	H01L2224/05499	9	Shape or distribution of the fillers	<administrative transfer to H10W 72/923 and H10W 72/925 simultaneously>
D	H01L2224/0554	5	External layer	<administrative transfer to H10W 72/923>
D	H01L2224/05541	6	Structure	<administrative transfer to H10W 72/921>
D	H01L2224/05546	7	Dual damascene structure	<administrative transfer to H10W 72/921>
D	H01L2224/05547	7	comprising a core and a coating	<administrative transfer to H10W 72/923>
D	H01L2224/05548	7	Bonding area integrally formed with a redistribution layer on the semiconductor or solid-state body	<administrative transfer to H10W 72/922>
D	H01L2224/0555	6	Shape	<administrative transfer to H10W 72/931>
D	H01L2224/05551	7	comprising apertures or cavities	<administrative transfer to H10W 72/931>
D	H01L2224/05552	7	in top view	<administrative transfer to H10W 72/932>
D	H01L2224/05553	8	being rectangular	<administrative transfer to H10W 72/932>
D	H01L2224/05554	8	being square	<administrative transfer to H10W 72/932>
D	H01L2224/05555	8	being circular or elliptic	<administrative transfer to H10W 72/932>
D	H01L2224/05556	7	in side view	<administrative transfer to H10W 72/934>
D	H01L2224/05557	8	comprising protrusions or indentations	<administrative transfer to H10W 72/934>
D	H01L2224/05558	8	conformal layer on a patterned surface	<administrative transfer to H10W 72/934>
D	H01L2224/05559	8	non conformal layer on a patterned surface	<administrative transfer to H10W 72/934>
D	H01L2224/0556	6	Disposition	<administrative transfer to H10W 72/941>
D	H01L2224/05561	7	On the entire surface of the internal layer	<administrative transfer to H10W 72/942>
D	H01L2224/05562	7	On the entire exposed surface of the internal layer	<administrative transfer to H10W 72/942>
D	H01L2224/05563	7	Only on parts of the surface of the internal layer	<administrative transfer to H10W 72/942>
D	H01L2224/05564	8	Only on the bonding interface of the bonding area	<administrative transfer to H10W 72/942>
D	H01L2224/05565	8	Only outside the bonding interface of the bonding area	<administrative transfer to H10W 72/942>

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D	H01L2224/05566	8	Both on and outside the bonding interface of the bonding area	<administrative transfer to H10W 72/942>
D	H01L2224/05567	7	the external layer being at least partially embedded in the surface	<administrative transfer to H10W 72/9415>
D	H01L2224/05568	7	the whole external layer protruding from the surface	<administrative transfer to H10W 72/9415>
D	H01L2224/05569	7	the external layer being disposed on a redistribution layer on the semiconductor or solid-state body	<administrative transfer to H10W 72/942>
D	H01L2224/0557	7	the external layer being disposed on a via connection of the semiconductor or solid-state body	<administrative transfer to H10W 72/942>
D	H01L2224/05571	7	the external layer being disposed in a recess of the surface	<administrative transfer to H10W 72/9415>
D	H01L2224/05572	8	the external layer extending out of an opening	<administrative transfer to H10W 72/9415>
D	H01L2224/05573	6	Single external layer	<administrative transfer to H10W 72/90>
D	H01L2224/05575	6	Plural external layers	<administrative transfer to H10W 72/923>
D	H01L2224/05576	7	being mutually engaged together, e.g. through inserts	<administrative transfer to H10W 72/923>
D	H01L2224/05578	7	being disposed next to each other, e.g. side-to-side arrangements	<administrative transfer to H10W 72/923>
D	H01L2224/0558	7	being stacked	<administrative transfer to H10W 72/923>
D	H01L2224/05582	8	Two-layer coating	<administrative transfer to H10W 72/923>
D	H01L2224/05583	8	Three-layer coating	<administrative transfer to H10W 72/923>
D	H01L2224/05584	8	Four-layer coating	<administrative transfer to H10W 72/923>
D	H01L2224/05599	6	Material	<administrative transfer to H10W 72/951>
D	H01L2224/056	7	with a principal constituent of the material being a metal or a metalloid, e.g. boron [B], silicon [Si], germanium [Ge], arsenic [As], antimony [Sb], tellurium [Te] and polonium [Po], and alloys thereof	<administrative transfer to H10W 72/952>
D	H01L2224/05601	8	the principal constituent melting at a temperature of less than 400°C	<administrative transfer to H10W 72/952>
D	H01L2224/05605	9	Gallium [Ga] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/05609	9	Indium [In] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/05611	9	Tin [Sn] as principal constituent	<administrative transfer to H10W 72/952>

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D	H01L2224/05613	9	Bismuth [Bi] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/05614	9	Thallium [Tl] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/05616	9	Lead [Pb] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/05617	8	the principal constituent melting at a temperature of greater than or equal to 400°C and less than 950°C	<administrative transfer to H10W 72/952>
D	H01L2224/05618	9	Zinc [Zn] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/0562	9	Antimony [Sb] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/05623	9	Magnesium [Mg] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/05624	9	Aluminium [Al] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/05638	8	the principal constituent melting at a temperature of greater than or equal to 950°C and less than 1550°C	<administrative transfer to H10W 72/952>
D	H01L2224/05639	9	Silver [Ag] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/05644	9	Gold [Au] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/05647	9	Copper [Cu] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/05649	9	Manganese [Mn] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/05655	9	Nickel [Ni] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/05657	9	Cobalt [Co] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/0566	9	Iron [Fe] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/05663	8	the principal constituent melting at a temperature of greater than 1550°C	<administrative transfer to H10W 72/952>
D	H01L2224/05664	9	Palladium [Pd] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/05666	9	Titanium [Ti] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/05669	9	Platinum [Pt] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/0567	9	Zirconium [Zr] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/05671	9	Chromium [Cr] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/05672	9	Vanadium [V] as principal constituent	<administrative transfer to H10W 72/952>

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D	H01L2224/05673	9	Rhodium [Rh] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/05676	9	Ruthenium [Ru] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/05678	9	Iridium [Ir] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/05679	9	Niobium [Nb] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/0568	9	Molybdenum [Mo] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/05681	9	Tantalum [Ta] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/05683	9	Rhenium [Re] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/05684	9	Tungsten [W] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/05686	7	with a principal constituent of the material being a non metallic, non metalloid inorganic material	<administrative transfer to H10W 72/953>
D	H01L2224/05687	8	Ceramics, e.g. crystalline carbides, nitrides or oxides	<administrative transfer to H10W 72/953>
D	H01L2224/05688	8	Glasses, e.g. amorphous oxides, nitrides or fluorides	<administrative transfer to H10W 72/953>
D	H01L2224/0569	7	with a principal constituent of the material being a polymer, e.g. polyester, phenolic based polymer, epoxy	<administrative transfer to H10W 72/953>
D	H01L2224/05691	8	The principal constituent being an elastomer, e.g. silicones, isoprene, neoprene	<administrative transfer to H10W 72/953>
D	H01L2224/05693	7	with a principal constituent of the material being a solid not provided for in groups H01L2224/056 - H01L2224/05691, e.g. allotropes of carbon, fullerene, graphite, carbon-nanotubes, diamond	<administrative transfer to H10W 72/953>
D	H01L2224/05694	7	with a principal constituent of the material being a liquid not provided for in groups H01L2224/056 - H01L2224/05691	<administrative transfer to H10W 72/953>
D	H01L2224/05695	7	with a principal constituent of the material being a gas not provided for in groups H01L2224/056 - H01L2224/05691	<administrative transfer to H10W 72/953>
D	H01L2224/05698	7	with a principal constituent of the material being a combination of two or more materials in the form of a matrix with a filler, i.e. being a hybrid material, e.g. segmented structures, foams	<administrative transfer to H10W 72/925>
D	H01L2224/05699	8	Material of the matrix	<administrative transfer to H10W 72/925 and H10W 72/951 simultaneously>

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D	H01L2224/057	9	with a principal constituent of the material being a metal or a metalloid, e.g. boron [B], silicon [Si], germanium [Ge], arsenic [As], antimony [Sb], tellurium [Te] and polonium [Po], and alloys thereof	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05701	10	the principal constituent melting at a temperature of less than 400°C	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05705	11	Gallium [Ga] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05709	11	Indium [In] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05711	11	Tin [Sn] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05713	11	Bismuth [Bi] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05714	11	Thallium [Tl] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05716	11	Lead [Pb] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05717	10	the principal constituent melting at a temperature of greater than or equal to 400°C and less than 950°C	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05718	11	Zinc [Zn] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/0572	11	Antimony [Sb] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05723	11	Magnesium [Mg] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>

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D	H01L2224/05724	11	Aluminium [Al] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05738	10	the principal constituent melting at a temperature of greater than or equal to 950°C and less than 1550°C	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05739	11	Silver [Ag] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05744	11	Gold [Au] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05747	11	Copper [Cu] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05749	11	Manganese [Mn] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05755	11	Nickel [Ni] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05757	11	Cobalt [Co] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/0576	11	Iron [Fe] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05763	10	the principal constituent melting at a temperature of greater than 1550°C	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05764	11	Palladium [Pd] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05766	11	Titanium [Ti] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05769	11	Platinum [Pt] as principal constituent	<administrative transfer to H10W 72/925 and

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				H10W 72/952 simultaneously>
D	H01L2224/0577	11	Zirconium [Zr] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05771	11	Chromium [Cr] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05772	11	Vanadium [V] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05773	11	Rhodium [Rh] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05776	11	Ruthenium [Ru] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05778	11	Iridium [Ir] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05779	11	Niobium [Nb] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/0578	11	Molybdenum [Mo] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05781	11	Tantalum [Ta] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05783	11	Rhenium [Re] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05784	11	Tungsten [W] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05786	9	with a principal constituent of the material being a non metallic, non metalloid inorganic material	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>

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D	H01L2224/05787	10	Ceramics, e.g. crystalline carbides, nitrides or oxides	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>
D	H01L2224/05788	10	Glasses, e.g. amorphous oxides, nitrides or fluorides	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>
D	H01L2224/0579	9	with a principal constituent of the material being a polymer, e.g. polyester, phenolic based polymer, epoxy	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>
D	H01L2224/05791	10	The principal constituent being an elastomer, e.g. silicones, isoprene, neoprene	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>
D	H01L2224/05793	9	with a principal constituent of the material being a solid not provided for in groups H01L2224/057 - H01L2224/05791, e.g. allotropes of carbon, fullerene, graphite, carbon-nanotubes, diamond	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>
D	H01L2224/05794	9	with a principal constituent of the material being a liquid not provided for in groups H01L2224/057 - H01L2224/05791	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>
D	H01L2224/05795	9	with a principal constituent of the material being a gas not provided for in groups H01L2224/057 - H01L2224/05791	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>
D	H01L2224/05798	8	Fillers	<administrative transfer to H10W 72/925>
D	H01L2224/05799	9	Base material	<administrative transfer to H10W 72/925 and H10W 72/951 simultaneously>
D	H01L2224/058	10	with a principal constituent of the material being a metal or a metalloid, e.g. boron [B], silicon [Si], germanium [Ge], arsenic [As], antimony [Sb], tellurium [Te] and polonium [Po], and alloys thereof	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05801	11	the principal constituent melting at a temperature of less than 400°C	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05805	12	Gallium [Ga] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05809	12	Indium [In] as principal constituent	<administrative transfer to H10W 72/925 and

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				H10W 72/952 simultaneously>
D	H01L2224/05811	12	Tin [Sn] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05813	12	Bismuth [Bi] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05814	12	Thallium [Tl] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05816	12	Lead [Pb] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05817	11	the principal constituent melting at a temperature of greater than or equal to 400°C and less than 950°C	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05818	12	Zinc [Zn] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/0582	12	Antimony [Sb] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05823	12	Magnesium [Mg] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05824	12	Aluminium [Al] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05838	11	the principal constituent melting at a temperature of greater than or equal to 950°C and less than 1550°C	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05839	12	Silver [Ag] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05844	12	Gold [Au] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>

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D	H01L2224/05847	12	Copper [Cu] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05849	12	Manganese [Mn] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05855	12	Nickel [Ni] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05857	12	Cobalt [Co] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/0586	12	Iron [Fe] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05863	11	the principal constituent melting at a temperature of greater than 1550°C	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05864	12	Palladium [Pd] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05866	12	Titanium [Ti] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05869	12	Platinum [Pt] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/0587	12	Zirconium [Zr] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05871	12	Chromium [Cr] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05872	12	Vanadium [V] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05873	12	Rhodium [Rh] as principal constituent	<administrative transfer to H10W 72/925 and

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				H10W 72/952 simultaneously>
D	H01L2224/05876	12	Ruthenium [Ru] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05878	12	Iridium [Ir] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05879	12	Niobium [Nb] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/0588	12	Molybdenum [Mo] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05881	12	Tantalum [Ta] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05883	12	Rhenium [Re] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05884	12	Tungsten [W] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05886	10	with a principal constituent of the material being a non metallic, non metalloid inorganic material	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>
D	H01L2224/05887	11	Ceramics, e.g. crystalline carbides, nitrides or oxides	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>
D	H01L2224/05888	11	Glasses, e.g. amorphous oxides, nitrides or fluorides	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>
D	H01L2224/0589	10	with a principal constituent of the material being a polymer, e.g. polyester, phenolic based polymer, epoxy	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>
D	H01L2224/05891	11	The principal constituent being an elastomer, e.g. silicones, isoprene, neoprene	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>

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D	H01L2224/05893	10	with a principal constituent of the material being a solid not provided for in groups H01L2224/058 - H01L2224/05891, e.g. allotropes of carbon, fullerene, graphite, carbon-nanotubes, diamond	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>
D	H01L2224/05894	10	with a principal constituent of the material being a liquid not provided for in groups H01L2224/058 - H01L2224/05891	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>
D	H01L2224/05895	10	with a principal constituent of the material being a gas not provided for in groups H01L2224/058 - H01L2224/05891	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>
D	H01L2224/05898	10	with a principal constituent of the material being a combination of two or more materials in the form of a matrix with a filler, i.e. being a hybrid material, e.g. segmented structures, foams	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>
D	H01L2224/05899	9	Coating material	<administrative transfer to H10W 72/925 and H10W 72/951 simultaneously>
D	H01L2224/059	10	with a principal constituent of the material being a metal or a metalloid, e.g. boron [B], silicon [Si], germanium [Ge], arsenic [As], antimony [Sb], tellurium [Te] and polonium [Po], and alloys thereof	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05901	11	the principal constituent melting at a temperature of less than 400°C	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05905	12	Gallium [Ga] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05909	12	Indium [In] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05911	12	Tin [Sn] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05913	12	Bismuth [Bi] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05914	12	Thallium [Tl] as principal constituent	<administrative transfer to H10W 72/925 and

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				H10W 72/952 simultaneously>
D	H01L2224/05916	12	Lead [Pb] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05917	11	the principal constituent melting at a temperature of greater than or equal to 400°C and less than 950°C	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05918	12	Zinc [Zn] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/0592	12	Antimony [Sb] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05923	12	Magnesium [Mg] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05924	12	Aluminium [Al] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05938	11	the principal constituent melting at a temperature of greater than or equal to 950°C and less than 1550°C	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05939	12	Silver [Ag] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05944	12	Gold [Au] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05947	12	Copper [Cu] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05949	12	Manganese [Mn] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05955	12	Nickel [Ni] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>

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D	H01L2224/05957	12	Cobalt [Co] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/0596	12	Iron [Fe] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05963	11	the principal constituent melting at a temperature of greater than 1550°C	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05964	12	Palladium [Pd] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05966	12	Titanium [Ti] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05969	12	Platinum [Pt] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/0597	12	Zirconium [Zr] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05971	12	Chromium [Cr] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05972	12	Vanadium [V] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05973	12	Rhodium [Rh] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05976	12	Ruthenium [Ru] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05978	12	Iridium [Ir] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05979	12	Niobium [Nb] as principal constituent	<administrative transfer to H10W 72/925 and

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				H10W 72/952 simultaneously>
D	H01L2224/0598	12	Molybdenum [Mo] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05981	12	Tantalum [Ta] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05983	12	Rhenium [Re] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05984	12	Tungsten [W] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/05986	10	with a principal constituent of the material being a non metallic, non metalloid inorganic material	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>
D	H01L2224/05987	11	Ceramics, e.g. crystalline carbides, nitrides or oxides	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>
D	H01L2224/05988	11	Glasses, e.g. amorphous oxides, nitrides or fluorides	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>
D	H01L2224/0599	10	with a principal constituent of the material being a polymer, e.g. polyester, phenolic based polymer, epoxy	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>
D	H01L2224/05991	11	The principal constituent being an elastomer, e.g. silicones, isoprene, neoprene	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>
D	H01L2224/05993	10	with a principal constituent of the material being a solid not provided for in groups H01L2224/059 - H01L2224/05991, e.g. allotropes of carbon, fullerene, graphite, carbon-nanotubes, diamond	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>
D	H01L2224/05994	10	with a principal constituent of the material being a liquid not provided for in groups H01L2224/059 - H01L2224/05991	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>
D	H01L2224/05995	10	with a principal constituent of the material being a gas not provided for in groups H01L2224/059 - H01L2224/05991	<administrative transfer to H10W 72/925 and

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				H10W 72/953 simultaneously>
D	H01L2224/05998	10	with a principal constituent of the material being a combination of two or more materials in the form of a matrix with a filler, i.e. being a hybrid material, e.g. segmented structures, foams	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>
D	H01L2224/05999	9	Shape or distribution of the fillers	<administrative transfer to H10W 72/925>
D	H01L2224/06	4	of a plurality of bonding areas	<administrative transfer to H10W 72/90>
D	H01L2224/0601	5	Structure	<administrative transfer to H10W 72/927>
D	H01L2224/0603	6	Bonding areas having different sizes, e.g. different heights or widths	<administrative transfer to H10W 72/926>
D	H01L2224/0605	5	Shape	<administrative transfer to H10W 72/936>
D	H01L2224/06051	6	Bonding areas having different shapes	<administrative transfer to H10W 72/936>
D	H01L2224/061	5	Disposition	<administrative transfer to H10W 72/944>
D	H01L2224/06102	6	the bonding areas being at different heights	<administrative transfer to H10W 72/944>
D	H01L2224/0612	6	Layout	<administrative transfer to H10W 72/9445>
D	H01L2224/0613	7	Square or rectangular array	<administrative transfer to H10W 72/9445>
D	H01L2224/06131	8	being uniform, i.e. having a uniform pitch across the array	<administrative transfer to H10W 72/9445>
D	H01L2224/06132	8	being non uniform, i.e. having a non uniform pitch across the array	<administrative transfer to H10W 72/9445>
D	H01L2224/06133	8	with a staggered arrangement, e.g. depopulated array	<administrative transfer to H10W 72/9445>
D	H01L2224/06134	8	covering only portions of the surface to be connected	<administrative transfer to H10W 72/9445>
D	H01L2224/06135	9	Covering only the peripheral area of the surface to be connected, i.e. peripheral arrangements	<administrative transfer to H10W 72/9445>
D	H01L2224/06136	9	Covering only the central area of the surface to be connected, i.e. central arrangements	<administrative transfer to H10W 72/9445>
D	H01L2224/06137	8	with specially adapted redistribution layers [RDL]	<administrative transfer to H10W 72/9445>
D	H01L2224/06138	9	being disposed in a single wiring level, i.e. planar layout	<administrative transfer to H10W 72/9445>
D	H01L2224/06139	9	being disposed in different wiring levels, i.e. resurf layout	<administrative transfer to H10W 72/9445>
D	H01L2224/0614	7	Circular array, i.e. array with radial symmetry	<administrative transfer to H10W 72/9445>

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D	H01L2224/06141	8	being uniform, i.e. having a uniform pitch across the array	<administrative transfer to H10W 72/9445>
D	H01L2224/06142	8	being non uniform, i.e. having a non uniform pitch across the array	<administrative transfer to H10W 72/9445>
D	H01L2224/06143	8	with a staggered arrangement, e.g. depopulated array	<administrative transfer to H10W 72/9445>
D	H01L2224/06144	8	covering only portions of the surface to be connected	<administrative transfer to H10W 72/9445>
D	H01L2224/06145	9	Covering only the peripheral area of the surface to be connected, i.e. peripheral arrangements	<administrative transfer to H10W 72/9445>
D	H01L2224/06146	9	Covering only the central area of the surface to be connected, i.e. central arrangements	<administrative transfer to H10W 72/9445>
D	H01L2224/06147	8	with specially adapted redistribution layers [RDL]	<administrative transfer to H10W 72/9445>
D	H01L2224/06148	9	being disposed in a single wiring level, i.e. planar layout	<administrative transfer to H10W 72/9445>
D	H01L2224/06149	9	being disposed in different wiring levels, i.e. resurf layout	<administrative transfer to H10W 72/9445>
D	H01L2224/0615	7	Mirror array, i.e. array having only a reflection symmetry, i.e. bilateral symmetry	<administrative transfer to H10W 72/9445>
D	H01L2224/06151	8	being uniform, i.e. having a uniform pitch across the array	<administrative transfer to H10W 72/9445>
D	H01L2224/06152	8	being non uniform, i.e. having a non uniform pitch across the array	<administrative transfer to H10W 72/9445>
D	H01L2224/06153	8	with a staggered arrangement, e.g. depopulated array	<administrative transfer to H10W 72/9445>
D	H01L2224/06154	8	covering only portions of the surface to be connected	<administrative transfer to H10W 72/9445>
D	H01L2224/06155	9	Covering only the peripheral area of the surface to be connected, i.e. peripheral arrangements	<administrative transfer to H10W 72/9445>
D	H01L2224/06156	9	Covering only the central area of the surface to be connected, i.e. central arrangements	<administrative transfer to H10W 72/9445>
D	H01L2224/06157	8	with specially adapted redistribution layers [RDL]	<administrative transfer to H10W 72/9445>
D	H01L2224/06158	9	being disposed in a single wiring level, i.e. planar layout	<administrative transfer to H10W 72/9445>
D	H01L2224/06159	9	being disposed in different wiring levels, i.e. resurf layout	<administrative transfer to H10W 72/9445>
D	H01L2224/0616	7	Random array, i.e. array with no symmetry	<administrative transfer to H10W 72/9445>
D	H01L2224/06163	8	with a staggered arrangement	<administrative transfer to H10W 72/9445>
D	H01L2224/06164	8	covering only portions of the surface to be connected	<administrative transfer to H10W 72/9445>

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D	H01L2224/06165	9	Covering only the peripheral area of the surface to be connected, i.e. peripheral arrangements	<administrative transfer to H10W 72/9445>
D	H01L2224/06166	9	Covering only the central area of the surface to be connected, i.e. central arrangements	<administrative transfer to H10W 72/9445>
D	H01L2224/06167	8	with specially adapted redistribution layers [RDL]	<administrative transfer to H10W 72/9445>
D	H01L2224/06168	9	being disposed in a single wiring level, i.e. planar layout	<administrative transfer to H10W 72/9445>
D	H01L2224/06169	9	being disposed in different wiring levels, i.e. resurf layout	<administrative transfer to H10W 72/9445>
D	H01L2224/06177	7	Combinations of arrays with different layouts	<administrative transfer to H10W 72/9445>
D	H01L2224/06179	7	Corner adaptations, i.e. disposition of the bonding areas at the corners of the semiconductor or solid-state body	<administrative transfer to H10W 72/9445>
D	H01L2224/0618	6	being disposed on at least two different sides of the body, e.g. dual array	<administrative transfer to H10W 72/944>
D	H01L2224/06181	7	On opposite sides of the body	<administrative transfer to H10W 72/944>
D	H01L2224/06182	8	with specially adapted redistribution layers [RDL]	<administrative transfer to H10W 72/944>
D	H01L2224/06183	7	On contiguous sides of the body	<administrative transfer to H10W 72/944>
D	H01L2224/06187	8	with specially adapted redistribution layers [RDL]	<administrative transfer to H10W 72/944>
D	H01L2224/06188	9	being disposed in a single wiring level, i.e. planar layout	<administrative transfer to H10W 72/944>
D	H01L2224/06189	9	being disposed in different wiring levels, i.e. resurf layout	<administrative transfer to H10W 72/944>
D	H01L2224/065	5	Material	<administrative transfer to H10W 72/957>
D	H01L2224/06505	6	Bonding areas having different materials	<administrative transfer to H10W 72/957>
D	H01L2224/0651	5	Function	<administrative transfer to H10W 72/967>
D	H01L2224/06515	6	Bonding areas having different functions	<administrative transfer to H10W 72/967>
D	H01L2224/06517	7	including bonding areas providing primarily mechanical bonding	<administrative transfer to H10W 72/967 and H10W 72/963 simultaneously>
D	H01L2224/06519	7	including bonding areas providing primarily thermal dissipation	<administrative transfer to H10W 72/967 and H10W 72/965 simultaneously>

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D	H01L2224/07	3	Structure, shape, material or disposition of the bonding areas after the connecting process	<administrative transfer to H10W 72/90>
D	H01L2224/08	4	of an individual bonding area	<administrative transfer to H10W 72/90>
D	H01L2224/0801	5	Structure	<administrative transfer to H10W 80/721>
D	H01L2224/0805	5	Shape	<administrative transfer to H10W 80/732>
D	H01L2224/08052	6	in top view	<administrative transfer to H10W 80/732 and H10W 72/932 simultaneously>
D	H01L2224/08053	7	being non uniform along the bonding area	<administrative transfer to H10W 80/732 and H10W 72/932 simultaneously>
D	H01L2224/08054	7	being rectangular	<administrative transfer to H10W 80/732 and H10W 72/932 simultaneously>
D	H01L2224/08055	7	being square	<administrative transfer to H10W 80/732 and H10W 72/932 simultaneously>
D	H01L2224/08056	7	being circular or elliptic	<administrative transfer to H10W 80/732 and H10W 72/932 simultaneously>
D	H01L2224/08057	6	in side view	<administrative transfer to H10W 80/732 and H10W 72/934 simultaneously>
D	H01L2224/08058	7	being non uniform along the bonding area	<administrative transfer to H10W 80/732 and H10W 72/934 simultaneously>
D	H01L2224/08059	7	comprising protrusions or indentations	<administrative transfer to H10W 80/732 and H10W 72/934 simultaneously>
D	H01L2224/0807	6	of bonding interfaces, e.g. interlocking features	<administrative transfer to H10W 80/732>
D	H01L2224/081	5	Disposition	<administrative transfer to H10W 80/743>
D	H01L2224/08111	6	the bonding area being disposed in a recess of the surface of the body	<administrative transfer to H10W 80/743 and H10W 72/9415 simultaneously>

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D	H01L2224/08112	6	the bonding area being at least partially embedded in the surface of the body	<administrative transfer to H10W 80/743 and H10W 72/9415 simultaneously>
D	H01L2224/08113	6	the whole bonding area protruding from the surface of the body	<administrative transfer to H10W 80/743 and H10W 72/9415 simultaneously>
D	H01L2224/0812	6	the bonding area connecting directly to another bonding area, i.e. connectorless bonding, e.g. bumpless bonding	<administrative transfer to H10W 80/701>
D	H01L2224/08121	7	the connected bonding areas being not aligned with respect to each other	<administrative transfer to H10W 80/701>
D	H01L2224/08123	7	the bonding area connecting directly to at least two bonding areas	<administrative transfer to H10W 80/701>
D	H01L2224/08135	7	the bonding area connecting between different semiconductor or solid-state bodies, i.e. chip-to-chip	<administrative transfer to H10W 90/791>
D	H01L2224/08137	8	the bodies being arranged next to each other, e.g. on a common substrate	<administrative transfer to H10W 90/792>
D	H01L2224/08145	8	the bodies being stacked	<administrative transfer to H10W 90/792>
D	H01L2224/08146	9	the bonding area connecting to a via connection in the body	<administrative transfer to H10W 90/792>
D	H01L2224/08147	9	the bonding area connecting to a bonding area disposed in a recess of the surface of the body	<administrative transfer to H10W 90/792>
D	H01L2224/08148	9	the bonding area connecting to a bonding area protruding from the surface of the body	<administrative transfer to H10W 90/792>
D	H01L2224/08151	7	the bonding area connecting between a semiconductor or solid-state body and an item not being a semiconductor or solid-state body, e.g. chip-to-substrate, chip-to-passive	<administrative transfer to H10W 90/791>
D	H01L2224/08153	8	the body and the item being arranged next to each other, e.g. on a common substrate	<administrative transfer to H10W 90/791>
D	H01L2224/08155	9	the item being non-metallic, e.g. being an insulating substrate with or without metallisation	<administrative transfer to H10W 90/794>
D	H01L2224/0816	10	the bonding area connecting to a pin of the item	<administrative transfer to H10W 90/794>
D	H01L2224/08163	10	the bonding area connecting to a potential ring of the item	<administrative transfer to H10W 90/794>
D	H01L2224/08165	10	the bonding area connecting to a via metallisation of the item	<administrative transfer to H10W 90/794>
D	H01L2224/08167	10	the bonding area connecting to a bonding area disposed in a recess of the surface of the item	<administrative transfer to H10W 90/794>
D	H01L2224/08168	10	the bonding area connecting to a bonding area protruding from the surface of the item	<administrative transfer to H10W 90/794>

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D	H01L2224/08175	9	the item being metallic	<administrative transfer to H10W 90/796>
D	H01L2224/08183	10	the bonding area connecting to a potential ring of the item	<administrative transfer to H10W 90/796>
D	H01L2224/08187	10	the bonding area connecting to a bonding area disposed in a recess of the surface of the item	<administrative transfer to H10W 90/796>
D	H01L2224/08188	10	the bonding area connecting to a bonding area protruding from the surface of the item	<administrative transfer to H10W 90/796>
D	H01L2224/08195	9	the item being a discrete passive component	<administrative transfer to H10W 90/798>
D	H01L2224/08197	10	the bonding area connecting to a bonding area disposed in a recess of the surface of the item	<administrative transfer to H10W 90/798>
D	H01L2224/08198	10	the bonding area connecting to a bonding area protruding from the surface of the item	<administrative transfer to H10W 90/798>
D	H01L2224/08221	8	the body and the item being stacked	<administrative transfer to H10W 90/791>
D	H01L2224/08225	9	the item being non-metallic, e.g. insulating substrate with or without metallisation	<administrative transfer to H10W 90/794>
D	H01L2224/0823	10	the bonding area connecting to a pin of the item	<administrative transfer to H10W 90/794>
D	H01L2224/08233	10	the bonding area connecting to a potential ring of the item	<administrative transfer to H10W 90/794>
D	H01L2224/08235	10	the bonding area connecting to a via metallisation of the item	<administrative transfer to H10W 90/794>
D	H01L2224/08237	10	the bonding area connecting to a bonding area disposed in a recess of the surface of the item	<administrative transfer to H10W 90/794>
D	H01L2224/08238	10	the bonding area connecting to a bonding area protruding from the surface of the item	<administrative transfer to H10W 90/794>
D	H01L2224/08245	9	the item being metallic	<administrative transfer to H10W 90/796>
D	H01L2224/08253	10	the bonding area connecting to a potential ring of the item	<administrative transfer to H10W 90/796>
D	H01L2224/08257	10	the bonding area connecting to a bonding area disposed in a recess of the surface of the item	<administrative transfer to H10W 90/796>
D	H01L2224/08258	10	the bonding area connecting to a bonding area protruding from the surface of the item	<administrative transfer to H10W 90/796>
D	H01L2224/08265	9	the item being a discrete passive component	<administrative transfer to H10W 90/798>
D	H01L2224/08267	10	the bonding area connecting to a bonding area disposed in a recess of the surface of the item	<administrative transfer to H10W 90/798>
D	H01L2224/08268	10	the bonding area connecting to a bonding area protruding from the surface of the item	<administrative transfer to H10W 90/798>

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D	H01L2224/085	5	Material	<administrative transfer to H10W 80/754>
D	H01L2224/08501	6	at the bonding interface	<administrative transfer to H10W 80/754>
D	H01L2224/08502	7	comprising an eutectic alloy	<administrative transfer to H10W 72/9524 and H10W 80/754 simultaneously>
D	H01L2224/08503	7	comprising an intermetallic compound	<administrative transfer to H10W 72/9528 and H10W 80/754 simultaneously>
D	H01L2224/08505	6	outside the bonding interface	<administrative transfer to H10W 80/754>
D	H01L2224/08506	7	comprising an eutectic alloy	<administrative transfer to H10W 72/9524 and H10W 80/754 simultaneously>
D	H01L2224/09	4	of a plurality of bonding areas	<administrative transfer to H10W 72/90>
D	H01L2224/0901	5	Structure	<administrative transfer to H10W 80/721 and H10W 72/927 simultaneously>
D	H01L2224/0903	6	Bonding areas having different sizes, e.g. different diameters, heights or widths	<administrative transfer to H10W 80/721 and H10W 72/926 simultaneously>
D	H01L2224/0905	5	Shape	<administrative transfer to H10W 72/936 and H10W 80/732 simultaneously>
D	H01L2224/09051	6	Bonding areas having different shapes	<administrative transfer to H10W 72/936 and H10W 80/732 simultaneously>
D	H01L2224/09055	7	of their bonding interfaces	<administrative transfer to H10W 72/936 and H10W 80/732 simultaneously>
D	H01L2224/091	5	Disposition	<administrative transfer to H10W 72/944 and H10W 80/743 simultaneously>
D	H01L2224/09102	6	the bonding areas being at different heights	<administrative transfer to H10W 72/944 and H10W 80/743 simultaneously>
D	H01L2224/09103	7	on the semiconductor or solid-state body	<administrative transfer to H10W 72/944 and

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				H10W 80/743 simultaneously>
D	H01L2224/09104	7	outside the semiconductor or solid-state body	<administrative transfer to H10W 72/944 and H10W 80/743 simultaneously>
D	H01L2224/0912	6	Layout	<administrative transfer to H10W 72/9445 and H10W 80/743 simultaneously>
D	H01L2224/0913	7	Square or rectangular array	<administrative transfer to H10W 72/9445 and H10W 80/743 simultaneously>
D	H01L2224/09132	8	being non uniform, i.e. having a non uniform pitch across the array	<administrative transfer to H10W 72/9445 and H10W 80/743 simultaneously>
D	H01L2224/09133	8	with a staggered arrangement, e.g. depopulated array	<administrative transfer to H10W 72/9445 and H10W 80/743 simultaneously>
D	H01L2224/09134	8	covering only portions of the surface to be connected	<administrative transfer to H10W 72/9445 and H10W 80/743 simultaneously>
D	H01L2224/09135	9	Covering only the peripheral area of the surface to be connected, i.e. peripheral arrangements	<administrative transfer to H10W 72/9445 and H10W 80/743 simultaneously>
D	H01L2224/0914	7	Circular array, i.e. array with radial symmetry	<administrative transfer to H10W 72/9445 and H10W 80/743 simultaneously>
D	H01L2224/09142	8	being non uniform, i.e. having a non uniform pitch across the array	<administrative transfer to H10W 72/9445 and H10W 80/743 simultaneously>
D	H01L2224/09143	8	with a staggered arrangement	<administrative transfer to H10W 72/9445 and H10W 80/743 simultaneously>
D	H01L2224/09144	8	covering only portions of the surface to be connected	<administrative transfer to H10W 72/9445 and H10W 80/743 simultaneously>
D	H01L2224/09145	9	Covering only the peripheral area of the surface to be connected, i.e. peripheral arrangements	<administrative transfer to H10W 72/9445 and H10W 80/743 simultaneously>

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D	H01L2224/0915	7	Mirror array, i.e. array having only a reflection symmetry, i.e. bilateral symmetry	<administrative transfer to H10W 72/9445 and H10W 80/743 simultaneously>
D	H01L2224/09151	8	being uniform, i.e. having a uniform pitch across the array	<administrative transfer to H10W 72/9445 and H10W 80/743 simultaneously>
D	H01L2224/09152	8	being non uniform, i.e. having a non uniform pitch across the array	<administrative transfer to H10W 72/9445 and H10W 80/743 simultaneously>
D	H01L2224/09153	8	with a staggered arrangement, e.g. depopulated array	<administrative transfer to H10W 72/9445 and H10W 80/743 simultaneously>
D	H01L2224/09154	8	covering only portions of the surface to be connected	<administrative transfer to H10W 72/9445 and H10W 80/743 simultaneously>
D	H01L2224/09155	9	Covering only the peripheral area of the surface to be connected, i.e. peripheral arrangements	<administrative transfer to H10W 72/9445 and H10W 80/743 simultaneously>
D	H01L2224/09156	9	Covering only the central area of the surface to be connected, i.e. central arrangements	<administrative transfer to H10W 72/9445 and H10W 80/743 simultaneously>
D	H01L2224/0916	7	Random array, i.e. array with no symmetry	<administrative transfer to H10W 72/9445 and H10W 80/743 simultaneously>
D	H01L2224/09163	8	with a staggered arrangement	<administrative transfer to H10W 72/9445 and H10W 80/743 simultaneously>
D	H01L2224/09164	8	covering only portions of the surface to be connected	<administrative transfer to H10W 72/9445 and H10W 80/743 simultaneously>
D	H01L2224/09165	9	Covering only the peripheral area of the surface to be connected, i.e. peripheral arrangements	<administrative transfer to H10W 72/9445 and H10W 80/743 simultaneously>
D	H01L2224/09177	7	Combinations of arrays with different layouts	<administrative transfer to H10W 72/9445 and H10W 80/743 simultaneously>

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D	H01L2224/09179	7	Corner adaptations, i.e. disposition of the bonding areas at the corners of the semiconductor or solid-state body	<administrative transfer to H10W 72/9445 and H10W 80/743 simultaneously>
D	H01L2224/0918	6	being disposed on at least two different sides of the body, e.g. dual array	<administrative transfer to H10W 72/944 and H10W 80/743 simultaneously>
D	H01L2224/09181	7	On opposite sides of the body	<administrative transfer to H10W 72/944 and H10W 80/743 simultaneously>
D	H01L2224/09183	7	On contiguous sides of the body	<administrative transfer to H10W 72/944 and H10W 80/743 simultaneously>
D	H01L2224/095	5	Material	<administrative transfer to H10W 72/957 and H10W 80/754 simultaneously>
D	H01L2224/09505	6	Bonding areas having different materials	<administrative transfer to H10W 72/957 and H10W 80/754 simultaneously>
D	H01L2224/0951	5	Function	<administrative transfer to H10W 72/967>
D	H01L2224/09515	6	Bonding areas having different functions	<administrative transfer to H10W 72/967>
D	H01L2224/09517	7	including bonding areas providing primarily mechanical support	<administrative transfer to H10W 72/967 and H10W 72/963 simultaneously>
D	H01L2224/09519	7	including bonding areas providing primarily thermal dissipation	<administrative transfer to H10W 72/967 and H10W 72/965 simultaneously>
D	H01L2224/10	2	Bump connectors; Manufacturing methods related thereto	<administrative transfer to H10W 72/20>
D	H01L2224/1012	3	Auxiliary members for bump connectors, e.g. spacers	<administrative transfer to H10W 72/281>
D	H01L2224/10122	4	being formed on the semiconductor or solid-state body to be connected	<administrative transfer to H10W 72/281>
D	H01L2224/10125	5	Reinforcing structures	<administrative transfer to H10W 72/283>
D	H01L2224/10126	6	Bump collar	<administrative transfer to H10W 72/283>
D	H01L2224/10135	5	Alignment aids	<administrative transfer to H10W 72/285>

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D	H01L2224/10145	5	Flow barriers	<administrative transfer to H10W 72/287>
D	H01L2224/10152	4	being formed on an item to be connected not being a semiconductor or solid-state body	<administrative transfer to H10W 72/281>
D	H01L2224/10155	5	Reinforcing structures	<administrative transfer to H10W 72/283>
D	H01L2224/10156	6	Bump collar	<administrative transfer to H10W 72/283>
D	H01L2224/10165	5	Alignment aids	<administrative transfer to H10W 72/285>
D	H01L2224/10175	5	Flow barriers	<administrative transfer to H10W 72/287>
D	H01L2224/11	3	Manufacturing methods	<administrative transfer to H10W 72/012>
D	H01L2224/11001	4	Involving a temporary auxiliary member not forming part of the manufacturing apparatus, e.g. removable or sacrificial coating, film or substrate	<administrative transfer to H10W 72/01204>
D	H01L2224/11002	5	for supporting the semiconductor or solid-state body	<administrative transfer to H10W 72/01204>
D	H01L2224/11003	5	for holding or transferring the bump preform	<administrative transfer to H10W 72/01204>
D	H01L2224/11005	5	for aligning the bump connector, e.g. marks, spacers	<administrative transfer to H10W 72/01204>
D	H01L2224/11009	5	for protecting parts during manufacture	<administrative transfer to H10W 72/01204>
D	H01L2224/11011	4	Involving a permanent auxiliary member, i.e. a member which is left at least partly in the finished device, e.g. coating, dummy feature	<administrative transfer to H10W 72/01208>
D	H01L2224/11013	5	for holding or confining the bump connector, e.g. solder flow barrier	<administrative transfer to H10W 72/01208>
D	H01L2224/11015	5	for aligning the bump connector, e.g. marks, spacers	<administrative transfer to H10W 72/01208>
D	H01L2224/11019	5	for protecting parts during the process	<administrative transfer to H10W 72/01208>
D	H01L2224/111	4	Manufacture and pre-treatment of the bump connector preform	<administrative transfer to H10W 72/01212>
D	H01L2224/1111	5	Shaping	<administrative transfer to H10W 72/01212>
D	H01L2224/1112	5	Applying permanent coating	<administrative transfer to H10W 72/01212>
D	H01L2224/113	4	by local deposition of the material of the bump connector	<administrative transfer to H10W 72/01221>
D	H01L2224/1131	5	in liquid form	<administrative transfer to H10W 72/01223>
D	H01L2224/11312	6	Continuous flow, e.g. using a microsyringe, a pump, a nozzle or extrusion	<administrative transfer to H10W 72/01223>

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D	H01L2224/11318	6	by dispensing droplets	<administrative transfer to H10W 72/01223>
D	H01L2224/1132	6	Screen printing, i.e. using a stencil	<administrative transfer to H10W 72/01223>
D	H01L2224/1133	5	in solid form	<administrative transfer to H10W 72/01225>
D	H01L2224/11332	6	using a powder	<administrative transfer to H10W 72/01225>
D	H01L2224/11334	6	using preformed bumps	<administrative transfer to H10W 72/01225>
D	H01L2224/1134	6	Stud bumping, i.e. using a wire-bonding apparatus	<administrative transfer to H10W 72/01225>
D	H01L2224/114	4	by blanket deposition of the material of the bump connector	<administrative transfer to H10W 72/01231>
D	H01L2224/1141	5	in liquid form	<administrative transfer to H10W 72/01233>
D	H01L2224/11416	6	Spin coating	<administrative transfer to H10W 72/01233>
D	H01L2224/11418	6	Spray coating	<administrative transfer to H10W 72/01233>
D	H01L2224/1142	6	Curtain coating	<administrative transfer to H10W 72/01233>
D	H01L2224/11422	6	by dipping, e.g. in a solder bath	<administrative transfer to H10W 72/01233>
D	H01L2224/11424	6	Immersion coating, e.g. in a solder bath	<administrative transfer to H10W 72/01233>
D	H01L2224/11426	6	Chemical solution deposition [CSD], i.e. using a liquid precursor	<administrative transfer to H10W 72/01233>
D	H01L2224/11428	6	Wave coating	<administrative transfer to H10W 72/01233>
D	H01L2224/1143	5	in solid form	<administrative transfer to H10W 72/01236>
D	H01L2224/11436	6	Lamination of a preform, e.g. foil, sheet or layer	<administrative transfer to H10W 72/01236>
D	H01L2224/11438	7	the preform being at least partly pre-pattered	<administrative transfer to H10W 72/01236>
D	H01L2224/1144	7	by transfer printing	<administrative transfer to H10W 72/01236>
D	H01L2224/11442	6	using a powder	<administrative transfer to H10W 72/01236>
D	H01L2224/11444	5	in gaseous form	<administrative transfer to H10W 72/01238>
D	H01L2224/1145	6	Physical vapour deposition [PVD], e.g. evaporation, or sputtering	<administrative transfer to H10W 72/01238>
D	H01L2224/11452	6	Chemical vapour deposition [CVD], e.g. laser CVD	<administrative transfer to H10W 72/01238>
D	H01L2224/1146	5	Plating	<administrative transfer to H10W 72/01235>

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D	H01L2224/11462	6	Electroplating	<administrative transfer to H10W 72/01235>
D	H01L2224/11464	6	Electroless plating	<administrative transfer to H10W 72/01235>
D	H01L2224/11466	5	Conformal deposition, i.e. blanket deposition of a conformal layer on a patterned surface	<administrative transfer to H10W 72/01231>
D	H01L2224/1147	4	using a lift-off mask	<administrative transfer to H10W 72/01255>
D	H01L2224/11472	5	Profile of the lift-off mask	<administrative transfer to H10W 72/01255>
D	H01L2224/11474	5	Multilayer masks	<administrative transfer to H10W 72/01255>
D	H01L2224/1148	5	Permanent masks, i.e. masks left in the finished device, e.g. passivation layers	<administrative transfer to H10W 72/01255>
D	H01L2224/115	4	by chemical or physical modification of a pre-existing or pre-deposited material	<administrative transfer to H10W 72/01261>
D	H01L2224/11502	5	Pre-existing or pre-deposited material	<administrative transfer to H10W 72/01261>
D	H01L2224/11505	5	Sintering	<administrative transfer to H10W 72/01261>
D	H01L2224/1151	5	Anodisation	<administrative transfer to H10W 72/01261>
D	H01L2224/11515	5	Curing and solidification, e.g. of a photosensitive bump material	<administrative transfer to H10W 72/01261>
D	H01L2224/1152	5	Self-assembly, e.g. self-agglomeration of the bump material in a fluid	<administrative transfer to H10W 72/01261>
D	H01L2224/11522	6	Auxiliary means therefor, e.g. for self-assembly activation	<administrative transfer to H10W 72/01261>
D	H01L2224/11524	6	with special adaptation of the surface or of an auxiliary substrate, e.g. surface shape specially adapted for the self-assembly process	<administrative transfer to H10W 72/01261>
D	H01L2224/11526	6	involving the material of the bonding area, e.g. bonding pad or under bump metallisation [UBM]	<administrative transfer to H10W 72/01261>
D	H01L2224/1155	5	Selective modification	<administrative transfer to H10W 72/01261>
D	H01L2224/11552	6	using a laser or a focussed ion beam [FIB]	<administrative transfer to H10W 72/01261>
D	H01L2224/11554	7	Stereolithography, i.e. solidification of a pattern defined by a laser trace in a photosensitive resin	<administrative transfer to H10W 72/01261>
D	H01L2224/116	4	by patterning a pre-deposited material	<administrative transfer to H10W 72/01251>
D	H01L2224/11602	5	Mechanical treatment, e.g. polishing, grinding	<administrative transfer to H10W 72/01251>
D	H01L2224/1161	5	Physical or chemical etching	<administrative transfer to H10W 72/01253>

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D	H01L2224/11612	6	by physical means only	<administrative transfer to H10W 72/01253>
D	H01L2224/11614	6	by chemical means only	<administrative transfer to H10W 72/01253>
D	H01L2224/11616	6	Chemical mechanical polishing [CMP]	<administrative transfer to H10W 72/01251>
D	H01L2224/11618	5	with selective exposure, development and removal of a photosensitive bump material, e.g. of a photosensitive conductive resin	<administrative transfer to H10W 72/01251>
D	H01L2224/1162	5	using masks	<administrative transfer to H10W 72/01255>
D	H01L2224/11622	6	Photolithography	<administrative transfer to H10W 72/01255>
D	H01L2224/1163	5	using a laser or a focused ion beam [FIB]	<administrative transfer to H10W 72/01251>
D	H01L2224/11632	6	Ablation by means of a laser or focused ion beam [FIB]	<administrative transfer to H10W 72/01251>
D	H01L2224/117	4	involving monitoring, e.g. feedback loop	<administrative transfer to H10W 72/012>
D	H01L2224/118	4	Post-treatment of the bump connector	<administrative transfer to H10W 72/012>
D	H01L2224/1181	5	Cleaning, e.g. oxide removal step, desmearing	<administrative transfer to H10W 72/01271>
D	H01L2224/1182	5	Applying permanent coating, e.g. in-situ coating	<administrative transfer to H10W 72/01215>
D	H01L2224/11821	6	Spray coating	<administrative transfer to H10W 72/01215>
D	H01L2224/11822	6	by dipping, e.g. in a solder bath	<administrative transfer to H10W 72/01215>
D	H01L2224/11823	6	Immersion coating, e.g. in a solder bath	<administrative transfer to H10W 72/01215>
D	H01L2224/11824	6	Chemical solution deposition [CSD], i.e. using a liquid precursor	<administrative transfer to H10W 72/01215>
D	H01L2224/11825	6	Plating, e.g. electroplating, electroless plating	<administrative transfer to H10W 72/01215>
D	H01L2224/11826	6	Physical vapour deposition [PVD], e.g. evaporation, or sputtering	<administrative transfer to H10W 72/01215>
D	H01L2224/11827	6	Chemical vapour deposition [CVD], e.g. laser CVD	<administrative transfer to H10W 72/01215>
D	H01L2224/1183	5	Reworking, e.g. shaping	<administrative transfer to H10W 72/01251>
D	H01L2224/11831	6	involving a chemical process, e.g. etching the bump connector	<administrative transfer to H10W 72/01251>
D	H01L2224/1184	6	involving a mechanical process, e.g. planarising the bump connector	<administrative transfer to H10W 72/01251>
D	H01L2224/11845	6	Chemical mechanical polishing [CMP]	<administrative transfer to H10W 72/01251>

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D	H01L2224/11848	5	Thermal treatments, e.g. annealing, controlled cooling	<administrative transfer to H10W 72/01265>
D	H01L2224/11849	6	Reflowing	<administrative transfer to H10W 72/01257>
D	H01L2224/119	4	Methods of manufacturing bump connectors involving a specific sequence of method steps	<administrative transfer to H10W 72/012>
D	H01L2224/11901	5	with repetition of the same manufacturing step	<administrative transfer to H10W 72/012>
D	H01L2224/11902	6	Multiple masking steps	<administrative transfer to H10W 72/012>
D	H01L2224/11903	7	using different masks	<administrative transfer to H10W 72/012>
D	H01L2224/11906	7	with modification of the same mask	<administrative transfer to H10W 72/012>
D	H01L2224/1191	5	Forming a passivation layer after forming the bump connector	<administrative transfer to H10W 72/012>
D	H01L2224/11912	5	the bump being used as a mask for patterning other parts	<administrative transfer to H10W 72/012>
D	H01L2224/11914	5	the under bump metallisation [UBM] being used as a mask for patterning other parts	<administrative transfer to H10W 72/012>
D	H01L2224/11916	5	a passivation layer being used as a mask for patterning other parts	<administrative transfer to H10W 72/012>
D	H01L2224/12	3	Structure, shape, material or disposition of the bump connectors prior to the connecting process	<administrative transfer to H10W 72/20>
D	H01L2224/12105	4	Bump connectors formed on an encapsulation of the semiconductor or solid-state body, e.g. bumps on chip-scale packages	<administrative transfer to H10W 72/241>
D	H01L2224/13	4	of an individual bump connector	<administrative transfer to H10W 72/20>
D	H01L2224/13001	5	Core members of the bump connector	<administrative transfer to H10W 72/20>
D	H01L2224/13005	6	Structure	<administrative transfer to H10W 72/221>
D	H01L2224/13006	7	Bump connector larger than the underlying bonding area, e.g. than the under bump metallisation [UBM]	<administrative transfer to H10W 72/221>
D	H01L2224/13007	7	Bump connector smaller than the underlying bonding area, e.g. than the under bump metallisation [UBM]	<administrative transfer to H10W 72/221>
D	H01L2224/13008	7	Bump connector integrally formed with a redistribution layer on the semiconductor or solid-state body	<administrative transfer to H10W 72/221>
D	H01L2224/13009	7	Bump connector integrally formed with a via connection of the semiconductor or solid-state body	<administrative transfer to H10W 72/221>
D	H01L2224/1301	6	Shape	<administrative transfer to H10W 72/231>

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D	H01L2224/13011	7	comprising apertures or cavities, e.g. hollow bump	<administrative transfer to H10W 72/231>
D	H01L2224/13012	7	in top view	<administrative transfer to H10W 72/232>
D	H01L2224/13013	8	being rectangular or square	<administrative transfer to H10W 72/232>
D	H01L2224/13014	8	being circular or elliptic	<administrative transfer to H10W 72/232>
D	H01L2224/13015	8	comprising protrusions or indentations	<administrative transfer to H10W 72/232>
D	H01L2224/13016	7	in side view	<administrative transfer to H10W 72/234>
D	H01L2224/13017	8	being non uniform along the bump connector	<administrative transfer to H10W 72/234>
D	H01L2224/13018	8	comprising protrusions or indentations	<administrative transfer to H10W 72/234>
D	H01L2224/13019	9	at the bonding interface of the bump connector, i.e. on the surface of the bump connector	<administrative transfer to H10W 72/234>
D	H01L2224/1302	6	Disposition	<administrative transfer to H10W 72/241>
D	H01L2224/13021	7	the bump connector being disposed in a recess of the surface	<administrative transfer to H10W 72/242>
D	H01L2224/13022	7	the bump connector being at least partially embedded in the surface	<administrative transfer to H10W 72/242>
D	H01L2224/13023	7	the whole bump connector protruding from the surface	<administrative transfer to H10W 72/242>
D	H01L2224/13024	7	the bump connector being disposed on a redistribution layer on the semiconductor or solid-state body	<administrative transfer to H10W 72/244>
D	H01L2224/13025	7	the bump connector being disposed on a via connection of the semiconductor or solid-state body	<administrative transfer to H10W 72/244>
D	H01L2224/13026	7	relative to the bonding area, e.g. bond pad, of the semiconductor or solid-state body	<administrative transfer to H10W 72/244>
D	H01L2224/13027	8	the bump connector being offset with respect to the bonding area, e.g. bond pad	<administrative transfer to H10W 72/244>
D	H01L2224/13028	8	the bump connector being disposed on at least two separate bonding areas, e.g. bond pads	<administrative transfer to H10W 72/244>
D	H01L2224/13075	6	Plural core members	<administrative transfer to H10W 72/224>
D	H01L2224/13076	7	being mutually engaged together, e.g. through inserts	<administrative transfer to H10W 72/224>
D	H01L2224/13078	7	being disposed next to each other, e.g. side-to-side arrangements	<administrative transfer to H10W 72/224>
D	H01L2224/1308	7	being stacked	<administrative transfer to H10W 72/222>

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D	H01L2224/13082	8	Two-layer arrangements	<administrative transfer to H10W 72/222>
D	H01L2224/13083	8	Three-layer arrangements	<administrative transfer to H10W 72/222>
D	H01L2224/13084	8	Four-layer arrangements	<administrative transfer to H10W 72/222>
D	H01L2224/13099	6	Material	<administrative transfer to H10W 72/251>
D	H01L2224/131	7	with a principal constituent of the material being a metal or a metalloid, e.g. boron [B], silicon [Si], germanium [Ge], arsenic [As], antimony [Sb], tellurium [Te] and polonium [Po], and alloys thereof	<administrative transfer to H10W 72/252>
D	H01L2224/13101	8	the principal constituent melting at a temperature of less than 400°C	<administrative transfer to H10W 72/252>
D	H01L2224/13105	9	Gallium [Ga] as principal constituent	<administrative transfer to H10W 72/252>
D	H01L2224/13109	9	Indium [In] as principal constituent	<administrative transfer to H10W 72/252>
D	H01L2224/13111	9	Tin [Sn] as principal constituent	<administrative transfer to H10W 72/252>
D	H01L2224/13113	9	Bismuth [Bi] as principal constituent	<administrative transfer to H10W 72/252>
D	H01L2224/13114	9	Thallium [Tl] as principal constituent	<administrative transfer to H10W 72/252>
D	H01L2224/13116	9	Lead [Pb] as principal constituent	<administrative transfer to H10W 72/252>
D	H01L2224/13117	8	the principal constituent melting at a temperature of greater than or equal to 400°C and less than 950°C	<administrative transfer to H10W 72/252>
D	H01L2224/13118	9	Zinc [Zn] as principal constituent	<administrative transfer to H10W 72/252>
D	H01L2224/1312	9	Antimony [Sb] as principal constituent	<administrative transfer to H10W 72/252>
D	H01L2224/13123	9	Magnesium [Mg] as principal constituent	<administrative transfer to H10W 72/252>
D	H01L2224/13124	9	Aluminium [Al] as principal constituent	<administrative transfer to H10W 72/252>
D	H01L2224/13138	8	the principal constituent melting at a temperature of greater than or equal to 950°C and less than 1550°C	<administrative transfer to H10W 72/252>
D	H01L2224/13139	9	Silver [Ag] as principal constituent	<administrative transfer to H10W 72/252>
D	H01L2224/13144	9	Gold [Au] as principal constituent	<administrative transfer to H10W 72/252>
D	H01L2224/13147	9	Copper [Cu] as principal constituent	<administrative transfer to H10W 72/252>

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D	H01L2224/13149	9	Manganese [Mn] as principal constituent	<administrative transfer to H10W 72/252>
D	H01L2224/13155	9	Nickel [Ni] as principal constituent	<administrative transfer to H10W 72/252>
D	H01L2224/13157	9	Cobalt [Co] as principal constituent	<administrative transfer to H10W 72/252>
D	H01L2224/1316	9	Iron [Fe] as principal constituent	<administrative transfer to H10W 72/252>
D	H01L2224/13163	8	the principal constituent melting at a temperature of greater than 1550°C	<administrative transfer to H10W 72/252>
D	H01L2224/13164	9	Palladium [Pd] as principal constituent	<administrative transfer to H10W 72/252>
D	H01L2224/13166	9	Titanium [Ti] as principal constituent	<administrative transfer to H10W 72/252>
D	H01L2224/13169	9	Platinum [Pt] as principal constituent	<administrative transfer to H10W 72/252>
D	H01L2224/1317	9	Zirconium [Zr] as principal constituent	<administrative transfer to H10W 72/252>
D	H01L2224/13171	9	Chromium [Cr] as principal constituent	<administrative transfer to H10W 72/252>
D	H01L2224/13172	9	Vanadium [V] as principal constituent	<administrative transfer to H10W 72/252>
D	H01L2224/13173	9	Rhodium [Rh] as principal constituent	<administrative transfer to H10W 72/252>
D	H01L2224/13176	9	Ruthenium [Ru] as principal constituent	<administrative transfer to H10W 72/252>
D	H01L2224/13178	9	Iridium [Ir] as principal constituent	<administrative transfer to H10W 72/252>
D	H01L2224/13179	9	Niobium [Nb] as principal constituent	<administrative transfer to H10W 72/252>
D	H01L2224/1318	9	Molybdenum [Mo] as principal constituent	<administrative transfer to H10W 72/252>
D	H01L2224/13181	9	Tantalum [Ta] as principal constituent	<administrative transfer to H10W 72/252>
D	H01L2224/13183	9	Rhenium [Re] as principal constituent	<administrative transfer to H10W 72/252>
D	H01L2224/13184	9	Tungsten [W] as principal constituent	<administrative transfer to H10W 72/252>
D	H01L2224/13186	7	with a principal constituent of the material being a non metallic, non metalloid inorganic material	<administrative transfer to H10W 72/253>
D	H01L2224/13187	8	Ceramics, e.g. crystalline carbides, nitrides or oxides	<administrative transfer to H10W 72/253>
D	H01L2224/13188	8	Glasses, e.g. amorphous oxides, nitrides or fluorides	<administrative transfer to H10W 72/253>
D	H01L2224/1319	7	with a principal constituent of the material being a polymer, e.g. polyester, phenolic based polymer, epoxy	<administrative transfer to H10W 72/253>

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D	H01L2224/13191	8	The principal constituent being an elastomer, e.g. silicones, isoprene, neoprene	<administrative transfer to H10W 72/253>
D	H01L2224/13193	7	with a principal constituent of the material being a solid not provided for in groups H01L2224/131 - H01L2224/13191, e.g. allotropes of carbon, fullerene, graphite, carbon-nanotubes, diamond	<administrative transfer to H10W 72/253>
D	H01L2224/13194	7	with a principal constituent of the material being a liquid not provided for in groups H01L2224/131 - H01L2224/13191	<administrative transfer to H10W 72/253>
D	H01L2224/13195	7	with a principal constituent of the material being a gas not provided for in groups H01L2224/131 - H01L2224/13191	<administrative transfer to H10W 72/253>
D	H01L2224/13198	7	with a principal constituent of the material being a combination of two or more materials in the form of a matrix with a filler, i.e. being a hybrid material, e.g. segmented structures, foams	<administrative transfer to H10W 72/225>
D	H01L2224/13199	8	Material of the matrix	<administrative transfer to H10W 72/225>
D	H01L2224/132	9	with a principal constituent of the material being a metal or a metalloid, e.g. boron [B], silicon [Si], germanium [Ge], arsenic [As], antimony [Sb], tellurium [Te] and polonium [Po], and alloys thereof	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L2224/13201	10	the principal constituent melting at a temperature of less than 400°C	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L2224/13205	11	Gallium [Ga] as principal constituent	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L2224/13209	11	Indium [In] as principal constituent	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L2224/13211	11	Tin [Sn] as principal constituent	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L2224/13213	11	Bismuth [Bi] as principal constituent	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L2224/13214	11	Thallium [Tl] as principal constituent	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>

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D	H01L2224/13216	11	Lead [Pb] as principal constituent	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L2224/13217	10	the principal constituent melting at a temperature of greater than or equal to 400°C and less than 950°C	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L2224/13218	11	Zinc [Zn] as principal constituent	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L2224/1322	11	Antimony [Sb] as principal constituent	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L2224/13223	11	Magnesium [Mg] as principal constituent	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L2224/13224	11	Aluminium [Al] as principal constituent	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L2224/13238	10	the principal constituent melting at a temperature of greater than or equal to 950°C and less than 1550°C	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L2224/13239	11	Silver [Ag] as principal constituent	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L2224/13244	11	Gold [Au] as principal constituent	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L2224/13247	11	Copper [Cu] as principal constituent	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L2224/13249	11	Manganese [Mn] as principal constituent	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L2224/13255	11	Nickel [Ni] as principal constituent	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L2224/13257	11	Cobalt [Co] as principal constituent	<administrative transfer to H10W 72/225 and

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				H10W 72/252 simultaneously>
D	H01L2224/1326	11	Iron [Fe] as principal constituent	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L2224/13263	10	the principal constituent melting at a temperature of greater than 1550°C	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L2224/13264	11	Palladium [Pd] as principal constituent	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L2224/13266	11	Titanium [Ti] as principal constituent	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L2224/13269	11	Platinum [Pt] as principal constituent	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L2224/1327	11	Zirconium [Zr] as principal constituent	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L2224/13271	11	Chromium [Cr] as principal constituent	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L2224/13272	11	Vanadium [V] as principal constituent	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L2224/13273	11	Rhodium [Rh] as principal constituent	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L2224/13276	11	Ruthenium [Ru] as principal constituent	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L2224/13278	11	Iridium [Ir] as principal constituent	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L2224/13279	11	Niobium [Nb] as principal constituent	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>

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D	H01L2224/1328	11	Molybdenum [Mo] as principal constituent	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L2224/13281	11	Tantalum [Ta] as principal constituent	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L2224/13283	11	Rhenium [Re] as principal constituent	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L2224/13284	11	Tungsten [W] as principal constituent	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L2224/13286	9	with a principal constituent of the material being a non metallic, non metalloid inorganic material	<administrative transfer to H10W 72/225 and H10W 72/253 simultaneously>
D	H01L2224/13287	10	Ceramics, e.g. crystalline carbides, nitrides or oxides	<administrative transfer to H10W 72/225 and H10W 72/253 simultaneously>
D	H01L2224/13288	10	Glasses, e.g. amorphous oxides, nitrides or fluorides	<administrative transfer to H10W 72/225 and H10W 72/253 simultaneously>
D	H01L2224/1329	9	with a principal constituent of the material being a polymer, e.g. polyester, phenolic based polymer, epoxy	<administrative transfer to H10W 72/225 and H10W 72/253 simultaneously>
D	H01L2224/13291	10	The principal constituent being an elastomer, e.g. silicones, isoprene, neoprene	<administrative transfer to H10W 72/225 and H10W 72/253 simultaneously>
D	H01L2224/13293	9	with a principal constituent of the material being a solid not provided for in groups H01L2224/132 - H01L2224/13291, e.g. allotropes of carbon, fullerene, graphite, carbon-nanotubes, diamond	<administrative transfer to H10W 72/225 and H10W 72/253 simultaneously>
D	H01L2224/13294	9	with a principal constituent of the material being a liquid not provided for in groups H01L2224/132 - H01L2224/13291	<administrative transfer to H10W 72/225 and H10W 72/253 simultaneously>
D	H01L2224/13295	9	with a principal constituent of the material being a gas not provided for in groups H01L2224/132 - H01L2224/13291	<administrative transfer to H10W 72/225 and H10W 72/253 simultaneously>

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D	H01L2224/13298	8	Fillers	<administrative transfer to H10W 72/225>
D	H01L2224/13299	9	Base material	<administrative transfer to H10W 72/225>
D	H01L2224/133	10	with a principal constituent of the material being a metal or a metalloid, e.g. boron [B], silicon [Si], germanium [Ge], arsenic [As], antimony [Sb], tellurium [Te] and polonium [Po], and alloys thereof	<administrative transfer to H10W 72/225>
D	H01L2224/13301	11	the principal constituent melting at a temperature of less than 400°C	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L2224/13305	12	Gallium [Ga] as principal constituent	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L2224/13309	12	Indium [In] as principal constituent	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L2224/13311	12	Tin [Sn] as principal constituent	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L2224/13313	12	Bismuth [Bi] as principal constituent	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L2224/13314	12	Thallium [Tl] as principal constituent	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L2224/13316	12	Lead [Pb] as principal constituent	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L2224/13317	11	the principal constituent melting at a temperature of greater than or equal to 400°C and less than 950°C	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L2224/13318	12	Zinc [Zn] as principal constituent	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L2224/1332	12	Antimony [Sb] as principal constituent	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>

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D	H01L2224/13323	12	Magnesium [Mg] as principal constituent	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L2224/13324	12	Aluminium [Al] as principal constituent	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L2224/13338	11	the principal constituent melting at a temperature of greater than or equal to 950°C and less than 1550°C	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L2224/13339	12	Silver [Ag] as principal constituent	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L2224/13344	12	Gold [Au] as principal constituent	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L2224/13347	12	Copper [Cu] as principal constituent	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L2224/13349	12	Manganese [Mn] as principal constituent	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L2224/13355	12	Nickel [Ni] as principal constituent	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L2224/13357	12	Cobalt [Co] as principal constituent	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L2224/1336	12	Iron [Fe] as principal constituent	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L2224/13363	11	the principal constituent melting at a temperature of greater than 1550°C	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L2224/13364	12	Palladium [Pd] as principal constituent	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L2224/13366	12	Titanium [Ti] as principal constituent	<administrative transfer to H10W 72/225 and

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				H10W 72/252 simultaneously>
D	H01L2224/13369	12	Platinum [Pt] as principal constituent	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L2224/1337	12	Zirconium [Zr] as principal constituent	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L2224/13371	12	Chromium [Cr] as principal constituent	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L2224/13372	12	Vanadium [V] as principal constituent	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L2224/13373	12	Rhodium [Rh] as principal constituent	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L2224/13376	12	Ruthenium [Ru] as principal constituent	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L2224/13378	12	Iridium [Ir] as principal constituent	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L2224/13379	12	Niobium [Nb] as principal constituent	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L2224/1338	12	Molybdenum [Mo] as principal constituent	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L2224/13381	12	Tantalum [Ta] as principal constituent	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L2224/13383	12	Rhenium [Re] as principal constituent	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L2224/13384	12	Tungsten [W] as principal constituent	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>

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D	H01L2224/13386	10	with a principal constituent of the material being a non metallic, non metalloid inorganic material	<administrative transfer to H10W 72/225 and H10W 72/253 simultaneously>
D	H01L2224/13387	11	Ceramics, e.g. crystalline carbides, nitrides or oxides	<administrative transfer to H10W 72/225 and H10W 72/253 simultaneously>
D	H01L2224/13388	11	Glasses, e.g. amorphous oxides, nitrides or fluorides	<administrative transfer to H10W 72/225 and H10W 72/253 simultaneously>
D	H01L2224/1339	10	with a principal constituent of the material being a polymer, e.g. polyester, phenolic based polymer, epoxy	<administrative transfer to H10W 72/225 and H10W 72/253 simultaneously>
D	H01L2224/13391	11	The principal constituent being an elastomer, e.g. silicones, isoprene, neoprene	<administrative transfer to H10W 72/225 and H10W 72/253 simultaneously>
D	H01L2224/13393	10	with a principal constituent of the material being a solid not provided for in groups H01L2224/133 - H01L2224/13391, e.g. allotropes of carbon, fullerene, graphite, carbon-nanotubes, diamond	<administrative transfer to H10W 72/225 and H10W 72/253 simultaneously>
D	H01L2224/13394	10	with a principal constituent of the material being a liquid not provided for in groups H01L2224/133 - H01L2224/13391	<administrative transfer to H10W 72/225 and H10W 72/253 simultaneously>
D	H01L2224/13395	10	with a principal constituent of the material being a gas not provided for in groups H01L2224/133 - H01L2224/13391	<administrative transfer to H10W 72/225 and H10W 72/253 simultaneously>
D	H01L2224/13398	10	with a principal constituent of the material being a combination of two or more materials in the form of a matrix with a filler, i.e. being a hybrid material, e.g. segmented structures, foams	<administrative transfer to H10W 72/225>
D	H01L2224/13399	9	Coating material	<administrative transfer to H10W 72/225>
D	H01L2224/134	10	with a principal constituent of the material being a metal or a metalloid, e.g. boron [B], silicon [Si], germanium [Ge], arsenic [As], antimony [Sb], tellurium [Te] and polonium [Po], and alloys thereof	<administrative transfer to H10W 72/225>
D	H01L2224/13401	11	the principal constituent melting at a temperature of less than 400°C	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>

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D	H01L2224/13405	12	Gallium [Ga] as principal constituent	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L2224/13409	12	Indium [In] as principal constituent	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L2224/13411	12	Tin [Sn] as principal constituent	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L2224/13413	12	Bismuth [Bi] as principal constituent	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L2224/13414	12	Thallium [Tl] as principal constituent	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L2224/13416	12	Lead [Pb] as principal constituent	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L2224/13417	11	the principal constituent melting at a temperature of greater than or equal to 400°C and less than 950°C	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L2224/13418	12	Zinc [Zn] as principal constituent	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L2224/1342	12	Antimony [Sb] as principal constituent	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L2224/13423	12	Magnesium [Mg] as principal constituent	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L2224/13424	12	Aluminium [Al] as principal constituent	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L2224/13438	11	the principal constituent melting at a temperature of greater than or equal to 950°C and less than 1550°C	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L2224/13439	12	Silver [Ag] as principal constituent	<administrative transfer to H10W 72/225 and

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				H10W 72/252 simultaneously>
D	H01L2224/13444	12	Gold [Au] as principal constituent	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L2224/13447	12	Copper [Cu] as principal constituent	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L2224/13449	12	Manganese [Mn] as principal constituent	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L2224/13455	12	Nickel [Ni] as principal constituent	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L2224/13457	12	Cobalt [Co] as principal constituent	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L2224/1346	12	Iron [Fe] as principal constituent	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L2224/13463	11	the principal constituent melting at a temperature of greater than 1550°C	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L2224/13464	12	Palladium [Pd] as principal constituent	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L2224/13466	12	Titanium [Ti] as principal constituent	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L2224/13469	12	Platinum [Pt] as principal constituent	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L2224/1347	12	Zirconium [Zr] as principal constituent	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L2224/13471	12	Chromium [Cr] as principal constituent	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>

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D	H01L2224/13472	12	Vanadium [V] as principal constituent	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L2224/13473	12	Rhodium [Rh] as principal constituent	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L2224/13476	12	Ruthenium [Ru] as principal constituent	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L2224/13478	12	Iridium [Ir] as principal constituent	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L2224/13479	12	Niobium [Nb] as principal constituent	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L2224/1348	12	Molybdenum [Mo] as principal constituent	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L2224/13481	12	Tantalum [Ta] as principal constituent	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L2224/13483	12	Rhenium [Re] as principal constituent	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L2224/13484	12	Tungsten [W] as principal constituent	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L2224/13486	10	with a principal constituent of the material being a non metallic, non metalloid inorganic material	<administrative transfer to H10W 72/225 and H10W 72/253 simultaneously>
D	H01L2224/13487	11	Ceramics, e.g. crystalline carbides, nitrides or oxides	<administrative transfer to H10W 72/225 and H10W 72/253 simultaneously>
D	H01L2224/13488	11	Glasses, e.g. amorphous oxides, nitrides or fluorides	<administrative transfer to H10W 72/225 and H10W 72/253 simultaneously>

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D	H01L2224/1349	10	with a principal constituent of the material being a polymer, e.g. polyester, phenolic based polymer, epoxy	<administrative transfer to H10W 72/225 and H10W 72/253 simultaneously>
D	H01L2224/13491	11	The principal constituent being an elastomer, e.g. silicones, isoprene, neoprene	<administrative transfer to H10W 72/225 and H10W 72/253 simultaneously>
D	H01L2224/13493	10	with a principal constituent of the material being a solid not provided for in groups H01L2224/134 - H01L2224/13491, e.g. allotropes of carbon, fullerene, graphite, carbon-nanotubes, diamond	<administrative transfer to H10W 72/225 and H10W 72/253 simultaneously>
D	H01L2224/13494	10	with a principal constituent of the material being a liquid not provided for in groups H01L2224/134 - H01L2224/13491	<administrative transfer to H10W 72/225 and H10W 72/253 simultaneously>
D	H01L2224/13495	10	with a principal constituent of the material being a gas not provided for in groups H01L2224/134 - H01L2224/13491	<administrative transfer to H10W 72/225 and H10W 72/253 simultaneously>
D	H01L2224/13498	10	with a principal constituent of the material being a combination of two or more materials in the form of a matrix with a filler, i.e. being a hybrid material, e.g. segmented structures, foams	<administrative transfer to H10W 72/225>
D	H01L2224/13499	9	Shape or distribution of the fillers	<administrative transfer to H10W 72/225>
D	H01L2224/1354	5	Coating	<administrative transfer to H10W 72/222>
D	H01L2224/13541	6	Structure	<administrative transfer to H10W 72/223>
D	H01L2224/1355	6	Shape	<administrative transfer to H10W 72/235>
D	H01L2224/13551	7	being non uniform	<administrative transfer to H10W 72/235>
D	H01L2224/13552	8	comprising protrusions or indentations	<administrative transfer to H10W 72/235>
D	H01L2224/13553	9	at the bonding interface of the bump connector, i.e. on the surface of the bump connector	<administrative transfer to H10W 72/235>
D	H01L2224/1356	6	Disposition	<administrative transfer to H10W 72/245>
D	H01L2224/13561	7	On the entire surface of the core, i.e. integral coating	<administrative transfer to H10W 72/245>
D	H01L2224/13562	7	On the entire exposed surface of the core	<administrative transfer to H10W 72/245>
D	H01L2224/13563	7	Only on parts of the surface of the core, i.e. partial coating	<administrative transfer to H10W 72/245>

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D	H01L2224/13564	8	Only on the bonding interface of the bump connector	<administrative transfer to H10W 72/245>
D	H01L2224/13565	8	Only outside the bonding interface of the bump connector	<administrative transfer to H10W 72/245>
D	H01L2224/13566	8	Both on and outside the bonding interface of the bump connector	<administrative transfer to H10W 72/245>
D	H01L2224/1357	6	Single coating layer	<administrative transfer to H10W 72/223>
D	H01L2224/13575	6	Plural coating layers	<administrative transfer to H10W 72/223>
D	H01L2224/13576	7	being mutually engaged together, e.g. through inserts	<administrative transfer to H10W 72/223>
D	H01L2224/13578	7	being disposed next to each other, e.g. side-to-side arrangements	<administrative transfer to H10W 72/223>
D	H01L2224/1358	7	being stacked	<administrative transfer to H10W 72/223>
D	H01L2224/13582	8	Two-layer coating	<administrative transfer to H10W 72/223>
D	H01L2224/13583	8	Three-layer coating	<administrative transfer to H10W 72/223>
D	H01L2224/13584	8	Four-layer coating	<administrative transfer to H10W 72/223>
D	H01L2224/13599	6	Material	<administrative transfer to H10W 72/255>
D	H01L2224/136	7	with a principal constituent of the material being a metal or a metalloid, e.g. boron [B], silicon [Si], germanium [Ge], arsenic [As], antimony [Sb], tellurium [Te] and polonium [Po], and alloys thereof	<administrative transfer to H10W 72/255>
D	H01L2224/13601	8	the principal constituent melting at a temperature of less than 400°C	<administrative transfer to H10W 72/255>
D	H01L2224/13605	9	Gallium [Ga] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13609	9	Indium [In] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13611	9	Tin [Sn] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13613	9	Bismuth [Bi] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13614	9	Thallium [Tl] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13616	9	Lead [Pb] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13617	8	the principal constituent melting at a temperature of greater than or equal to 400°C and less than 950°C	<administrative transfer to H10W 72/255>
D	H01L2224/13618	9	Zinc [Zn] as principal constituent	<administrative transfer to H10W 72/255>

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D	H01L2224/1362	9	Antimony [Sb] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13623	9	Magnesium [Mg] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13624	9	Aluminium [Al] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13638	8	the principal constituent melting at a temperature of greater than or equal to 950°C and less than 1550°C	<administrative transfer to H10W 72/255>
D	H01L2224/13639	9	Silver [Ag] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13644	9	Gold [Au] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13647	9	Copper [Cu] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13649	9	Manganese [Mn] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13655	9	Nickel [Ni] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13657	9	Cobalt [Co] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/1366	9	Iron [Fe] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13663	8	the principal constituent melting at a temperature of greater than 1550°C	<administrative transfer to H10W 72/255>
D	H01L2224/13664	9	Palladium [Pd] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13666	9	Titanium [Ti] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13669	9	Platinum [Pt] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/1367	9	Zirconium [Zr] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13671	9	Chromium [Cr] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13672	9	Vanadium [V] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13673	9	Rhodium [Rh] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13676	9	Ruthenium [Ru] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13678	9	Iridium [Ir] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13679	9	Niobium [Nb] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/1368	9	Molybdenum [Mo] as principal constituent	<administrative transfer to H10W 72/255>

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D	H01L2224/13681	9	Tantalum [Ta] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13683	9	Rhenium [Re] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13684	9	Tungsten [W] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13686	7	with a principal constituent of the material being a non metallic, non metalloid inorganic material	<administrative transfer to H10W 72/255>
D	H01L2224/13687	8	Ceramics, e.g. crystalline carbides, nitrides or oxides	<administrative transfer to H10W 72/255>
D	H01L2224/13688	8	Glasses, e.g. amorphous oxides, nitrides or fluorides	<administrative transfer to H10W 72/255>
D	H01L2224/1369	7	with a principal constituent of the material being a polymer, e.g. polyester, phenolic based polymer, epoxy	<administrative transfer to H10W 72/255>
D	H01L2224/13691	8	The principal constituent being an elastomer, e.g. silicones, isoprene, neoprene	<administrative transfer to H10W 72/255>
D	H01L2224/13693	7	with a principal constituent of the material being a solid not provided for in groups H01L2224/136 - H01L2224/13691, e.g. allotropes of carbon, fullerene, graphite, carbon-nanotubes, diamond	<administrative transfer to H10W 72/255>
D	H01L2224/13694	7	with a principal constituent of the material being a liquid not provided for in groups H01L2224/136 - H01L2224/13691	<administrative transfer to H10W 72/255>
D	H01L2224/13695	7	with a principal constituent of the material being a gas not provided for in groups H01L2224/136 - H01L2224/13691	<administrative transfer to H10W 72/255>
D	H01L2224/13698	7	with a principal constituent of the material being a combination of two or more materials in the form of a matrix with a filler, i.e. being a hybrid material, e.g. segmented structures, foams	<administrative transfer to H10W 72/255>
D	H01L2224/13699	8	Material of the matrix	<administrative transfer to H10W 72/255>
D	H01L2224/137	9	with a principal constituent of the material being a metal or a metalloid, e.g. boron [B], silicon [Si], germanium [Ge], arsenic [As], antimony [Sb], tellurium [Te] and polonium [Po], and alloys thereof	<administrative transfer to H10W 72/255>
D	H01L2224/13701	10	the principal constituent melting at a temperature of less than 400°C	<administrative transfer to H10W 72/255>
D	H01L2224/13705	11	Gallium [Ga] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13709	11	Indium [In] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13711	11	Tin [Sn] as principal constituent	<administrative transfer to H10W 72/255>

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D	H01L2224/13713	11	Bismuth [Bi] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13714	11	Thallium [Tl] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13716	11	Lead [Pb] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13717	10	the principal constituent melting at a temperature of greater than or equal to 400°C and less than 950°C	<administrative transfer to H10W 72/255>
D	H01L2224/13718	11	Zinc [Zn] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/1372	11	Antimony [Sb] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13723	11	Magnesium [Mg] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13724	11	Aluminium [Al] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13738	10	the principal constituent melting at a temperature of greater than or equal to 950°C and less than 1550°C	<administrative transfer to H10W 72/255>
D	H01L2224/13739	11	Silver [Ag] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13744	11	Gold [Au] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13747	11	Copper [Cu] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13749	11	Manganese [Mn] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13755	11	Nickel [Ni] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13757	11	Cobalt [Co] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/1376	11	Iron [Fe] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13763	10	the principal constituent melting at a temperature of greater than 1550°C	<administrative transfer to H10W 72/255>
D	H01L2224/13764	11	Palladium [Pd] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13766	11	Titanium [Ti] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13769	11	Platinum [Pt] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/1377	11	Zirconium [Zr] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13771	11	Chromium [Cr] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13772	11	Vanadium [V] as principal constituent	<administrative transfer to H10W 72/255>

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D	H01L2224/13773	11	Rhodium [Rh] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13776	11	Ruthenium [Ru] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13778	11	Iridium [Ir] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13779	11	Niobium [Nb] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/1378	11	Molybdenum [Mo] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13781	11	Tantalum [Ta] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13783	11	Rhenium [Re] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13784	11	Tungsten [W] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13786	9	with a principal constituent of the material being a non metallic, non metalloid inorganic material	<administrative transfer to H10W 72/255>
D	H01L2224/13787	10	Ceramics, e.g. crystalline carbides, nitrides or oxides	<administrative transfer to H10W 72/255>
D	H01L2224/13788	10	Glasses, e.g. amorphous oxides, nitrides or fluorides	<administrative transfer to H10W 72/255>
D	H01L2224/1379	9	with a principal constituent of the material being a polymer, e.g. polyester, phenolic based polymer, epoxy	<administrative transfer to H10W 72/255>
D	H01L2224/13791	10	The principal constituent being an elastomer, e.g. silicones, isoprene, neoprene	<administrative transfer to H10W 72/255>
D	H01L2224/13793	9	with a principal constituent of the material being a solid not provided for in groups H01L2224/137 - H01L2224/13791, e.g. allotropes of carbon, fullerene, graphite, carbon-nanotubes, diamond	<administrative transfer to H10W 72/255>
D	H01L2224/13794	9	with a principal constituent of the material being a liquid not provided for in groups H01L2224/137 - H01L2224/13791	<administrative transfer to H10W 72/255>
D	H01L2224/13795	9	with a principal constituent of the material being a gas not provided for in groups H01L2224/137 - H01L2224/13791	<administrative transfer to H10W 72/255>
D	H01L2224/13798	8	Fillers	<administrative transfer to H10W 72/255>
D	H01L2224/13799	9	Base material	<administrative transfer to H10W 72/255>
D	H01L2224/138	10	with a principal constituent of the material being a metal or a metalloid, e.g. boron [B], silicon [Si], germanium [Ge], arsenic [As], antimony [Sb], tellurium [Te] and polonium [Po], and alloys thereof	<administrative transfer to H10W 72/255>

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D	H01L2224/13801	11	the principal constituent melting at a temperature of less than 400°C	<administrative transfer to H10W 72/255>
D	H01L2224/13805	12	Gallium [Ga] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13809	12	Indium [In] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13811	12	Tin [Sn] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13813	12	Bismuth [Bi] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13814	12	Thallium [Tl] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13816	12	Lead [Pb] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13817	11	the principal constituent melting at a temperature of greater than or equal to 400°C and less than 950°C	<administrative transfer to H10W 72/255>
D	H01L2224/13818	12	Zinc [Zn] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/1382	12	Antimony [Sb] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13823	12	Magnesium [Mg] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13824	12	Aluminium [Al] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13838	11	the principal constituent melting at a temperature of greater than or equal to 950°C and less than 1550°C	<administrative transfer to H10W 72/255>
D	H01L2224/13839	12	Silver [Ag] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13844	12	Gold [Au] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13847	12	Copper [Cu] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13849	12	Manganese [Mn] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13855	12	Nickel [Ni] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13857	12	Cobalt [Co] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/1386	12	Iron [Fe] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13863	11	the principal constituent melting at a temperature of greater than 1550°C	<administrative transfer to H10W 72/255>
D	H01L2224/13864	12	Palladium [Pd] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13866	12	Titanium [Ti] as principal constituent	<administrative transfer to H10W 72/255>

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D	H01L2224/13869	12	Platinum [Pt] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/1387	12	Zirconium [Zr] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13871	12	Chromium [Cr] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13872	12	Vanadium [V] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13873	12	Rhodium [Rh] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13876	12	Ruthenium [Ru] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13878	12	Iridium [Ir] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13879	12	Niobium [Nb] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/1388	12	Molybdenum [Mo] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13881	12	Tantalum [Ta] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13883	12	Rhenium [Re] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13884	12	Tungsten [W] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13886	10	with a principal constituent of the material being a non metallic, non metalloid inorganic material	<administrative transfer to H10W 72/255>
D	H01L2224/13887	11	Ceramics, e.g. crystalline carbides, nitrides or oxides	<administrative transfer to H10W 72/255>
D	H01L2224/13888	11	Glasses, e.g. amorphous oxides, nitrides or fluorides	<administrative transfer to H10W 72/255>
D	H01L2224/1389	10	with a principal constituent of the material being a polymer, e.g. polyester, phenolic based polymer, epoxy	<administrative transfer to H10W 72/255>
D	H01L2224/13891	11	The principal constituent being an elastomer, e.g. silicones, isoprene, neoprene	<administrative transfer to H10W 72/255>
D	H01L2224/13893	10	with a principal constituent of the material being a solid not provided for in groups H01L2224/138 - H01L2224/13891, e.g. allotropes of carbon, fullerene, graphite, carbon-nanotubes, diamond	<administrative transfer to H10W 72/255>
D	H01L2224/13894	10	with a principal constituent of the material being a liquid not provided for in groups H01L2224/138 - H01L2224/13891	<administrative transfer to H10W 72/255>
D	H01L2224/13895	10	with a principal constituent of the material being a gas not provided for in groups H01L2224/138 - H01L2224/13891	<administrative transfer to H10W 72/255>

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D	H01L2224/13898	10	with a principal constituent of the material being a combination of two or more materials in the form of a matrix with a filler, i.e. being a hybrid material, e.g. segmented structures, foams	<administrative transfer to H10W 72/255>
D	H01L2224/13899	9	Coating material	<administrative transfer to H10W 72/255>
D	H01L2224/139	10	with a principal constituent of the material being a metal or a metalloid, e.g. boron [B], silicon [Si], germanium [Ge], arsenic [As], antimony [Sb], tellurium [Te] and polonium [Po], and alloys thereof	<administrative transfer to H10W 72/255>
D	H01L2224/13901	11	the principal constituent melting at a temperature of less than 400°C	<administrative transfer to H10W 72/255>
D	H01L2224/13905	12	Gallium [Ga] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13909	12	Indium [In] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13911	12	Tin [Sn] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13913	12	Bismuth [Bi] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13914	12	Thallium [Tl] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13916	12	Lead [Pb] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13917	11	the principal constituent melting at a temperature of greater than or equal to 400°C and less than 950°C	<administrative transfer to H10W 72/255>
D	H01L2224/13918	12	Zinc [Zn] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/1392	12	Antimony [Sb] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13923	12	Magnesium [Mg] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13924	12	Aluminium [Al] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13938	11	the principal constituent melting at a temperature of greater than or equal to 950°C and less than 1550°C	<administrative transfer to H10W 72/255>
D	H01L2224/13939	12	Silver [Ag] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13944	12	Gold [Au] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13947	12	Copper [Cu] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13949	12	Manganese [Mn] as principal constituent	<administrative transfer to H10W 72/255>

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D	H01L2224/13955	12	Nickel [Ni] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13957	12	Cobalt [Co] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/1396	12	Iron [Fe] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13963	11	the principal constituent melting at a temperature of greater than 1550°C	<administrative transfer to H10W 72/255>
D	H01L2224/13964	12	Palladium [Pd] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13966	12	Titanium [Ti] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13969	12	Platinum [Pt] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/1397	12	Zirconium [Zr] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13971	12	Chromium [Cr] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13972	12	Vanadium [V] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13973	12	Rhodium [Rh] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13976	12	Ruthenium [Ru] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13978	12	Iridium [Ir] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13979	12	Niobium [Nb] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/1398	12	Molybdenum [Mo] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13981	12	Tantalum [Ta] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13983	12	Rhenium [Re] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13984	12	Tungsten [W] as principal constituent	<administrative transfer to H10W 72/255>
D	H01L2224/13986	10	with a principal constituent of the material being a non metallic, non metalloid inorganic material	<administrative transfer to H10W 72/255>
D	H01L2224/13987	11	Ceramics, e.g. crystalline carbides, nitrides or oxides	<administrative transfer to H10W 72/255>
D	H01L2224/13988	11	Glasses, e.g. amorphous oxides, nitrides or fluorides	<administrative transfer to H10W 72/255>
D	H01L2224/1399	10	with a principal constituent of the material being a polymer, e.g. polyester, phenolic based polymer, epoxy	<administrative transfer to H10W 72/255>
D	H01L2224/13991	11	The principal constituent being an elastomer, e.g. silicones, isoprene, neoprene	<administrative transfer to H10W 72/255>

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D	H01L2224/13993	10	with a principal constituent of the material being a solid not provided for in groups H01L2224/139 - H01L2224/13991, e.g. allotropes of carbon, fullerene, graphite, carbon-nanotubes, diamond	<administrative transfer to H10W 72/255>
D	H01L2224/13994	10	with a principal constituent of the material being a liquid not provided for in groups H01L2224/139 - H01L2224/13991	<administrative transfer to H10W 72/255>
D	H01L2224/13995	10	with a principal constituent of the material being a gas not provided for in groups H01L2224/139 - H01L2224/13991	<administrative transfer to H10W 72/255>
D	H01L2224/13998	10	with a principal constituent of the material being a combination of two or more materials in the form of a matrix with a filler, i.e. being a hybrid material, e.g. segmented structures, foams	<administrative transfer to H10W 72/255>
D	H01L2224/13999	9	Shape or distribution of the fillers	<administrative transfer to H10W 72/255>
D	H01L2224/14	4	of a plurality of bump connectors	<administrative transfer to H10W 72/20>
D	H01L2224/1401	5	Structure	<administrative transfer to H10W 72/228>
D	H01L2224/1403	6	Bump connectors having different sizes, e.g. different diameters, heights or widths	<administrative transfer to H10W 72/227>
D	H01L2224/1405	5	Shape	<administrative transfer to H10W 72/231>
D	H01L2224/14051	6	Bump connectors having different shapes	<administrative transfer to H10W 72/237>
D	H01L2224/141	5	Disposition	<administrative transfer to H10W 72/247>
D	H01L2224/14104	6	relative to the bonding areas, e.g. bond pads, of the semiconductor or solid-state body	<administrative transfer to H10W 72/244 and H10W 72/247 simultaneously>
D	H01L2224/1411	7	the bump connectors being bonded to at least one common bonding area	<administrative transfer to H10W 72/244 and H10W 72/247 simultaneously>
D	H01L2224/1412	6	Layout	<administrative transfer to H10W 72/248>
D	H01L2224/1413	7	Square or rectangular array	<administrative transfer to H10W 72/248>
D	H01L2224/14131	8	being uniform, i.e. having a uniform pitch across the array	<administrative transfer to H10W 72/248>
D	H01L2224/14132	8	being non uniform, i.e. having a non uniform pitch across the array	<administrative transfer to H10W 72/248>
D	H01L2224/14133	8	with a staggered arrangement, e.g. depopulated array	<administrative transfer to H10W 72/248>

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D	H01L2224/14134	8	covering only portions of the surface to be connected	<administrative transfer to H10W 72/248>
D	H01L2224/14135	9	Covering only the peripheral area of the surface to be connected, i.e. peripheral arrangements	<administrative transfer to H10W 72/248>
D	H01L2224/14136	9	Covering only the central area of the surface to be connected, i.e. central arrangements	<administrative transfer to H10W 72/248>
D	H01L2224/1414	7	Circular array, i.e. array with radial symmetry	<administrative transfer to H10W 72/248>
D	H01L2224/14141	8	being uniform, i.e. having a uniform pitch across the array	<administrative transfer to H10W 72/248>
D	H01L2224/14142	8	being non uniform, i.e. having a non uniform pitch across the array	<administrative transfer to H10W 72/248>
D	H01L2224/14143	8	with a staggered arrangement, e.g. depopulated array	<administrative transfer to H10W 72/248>
D	H01L2224/14144	9	covering only portions of the surface to be connected	<administrative transfer to H10W 72/248>
D	H01L2224/14145	9	Covering only the peripheral area of the surface to be connected, i.e. peripheral arrangements	<administrative transfer to H10W 72/248>
D	H01L2224/14146	9	Covering only the central area of the surface to be connected, i.e. central arrangements	<administrative transfer to H10W 72/248>
D	H01L2224/1415	7	Mirror array, i.e. array having only a reflection symmetry, i.e. bilateral symmetry	<administrative transfer to H10W 72/248>
D	H01L2224/14151	8	being uniform, i.e. having a uniform pitch across the array	<administrative transfer to H10W 72/248>
D	H01L2224/14152	8	being non uniform, i.e. having a non uniform pitch across the array	<administrative transfer to H10W 72/248>
D	H01L2224/14153	8	with a staggered arrangement, e.g. depopulated array	<administrative transfer to H10W 72/248>
D	H01L2224/14154	8	covering only portions of the surface to be connected	<administrative transfer to H10W 72/248>
D	H01L2224/14155	9	Covering only the peripheral area of the surface to be connected, i.e. peripheral arrangements	<administrative transfer to H10W 72/248>
D	H01L2224/14156	9	Covering only the central area of the surface to be connected, i.e. central arrangements	<administrative transfer to H10W 72/248>
D	H01L2224/1416	7	Random layout, i.e. layout with no symmetry	<administrative transfer to H10W 72/248>
D	H01L2224/14163	8	with a staggered arrangement	<administrative transfer to H10W 72/248>
D	H01L2224/14164	8	covering only portions of the surface to be connected	<administrative transfer to H10W 72/248>
D	H01L2224/14165	9	Covering only the peripheral area of the surface to be connected, i.e. peripheral arrangements	<administrative transfer to H10W 72/248>
D	H01L2224/14166	9	Covering only the central area of the surface to be connected, i.e. central arrangements	<administrative transfer to H10W 72/248>

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D	H01L2224/14177	7	Combinations of arrays with different layouts	<administrative transfer to H10W 72/248>
D	H01L2224/14179	7	Corner adaptations, i.e. disposition of the bump connectors at the corners of the semiconductor or solid-state body	<administrative transfer to H10W 72/248>
D	H01L2224/1418	6	being disposed on at least two different sides of the body, e.g. dual array	<administrative transfer to H10W 72/248>
D	H01L2224/14181	7	On opposite sides of the body	<administrative transfer to H10W 72/248>
D	H01L2224/14183	7	On contiguous sides of the body	<administrative transfer to H10W 72/248>
D	H01L2224/145	5	Material	<administrative transfer to H10W 72/248>
D	H01L2224/14505	6	Bump connectors having different materials	<administrative transfer to H10W 72/257>
D	H01L2224/1451	5	Function	<administrative transfer to H10W 72/261>
D	H01L2224/14515	6	Bump connectors having different functions	<administrative transfer to H10W 72/267>
D	H01L2224/14517	7	including bump connectors providing primarily mechanical bonding	<administrative transfer to H10W 72/267 and H10W 72/263 simultaneously>
D	H01L2224/14519	7	including bump connectors providing primarily thermal dissipation	<administrative transfer to H10W 72/267 and H10W 72/265 simultaneously>
D	H01L2224/15	3	Structure, shape, material or disposition of the bump connectors after the connecting process	<administrative transfer to H10W 72/07251 and H10W 72/20 simultaneously>
D	H01L2224/16	4	of an individual bump connector	<administrative transfer to H10W 72/07251 and H10W 72/20 simultaneously>
D	H01L2224/1601	5	Structure	<administrative transfer to H10W 72/07252 and H10W 72/221 simultaneously>
D	H01L2224/16012	6	relative to the bonding area, e.g. bond pad	<administrative transfer to H10W 72/07252 and H10W 72/221 simultaneously>
D	H01L2224/16013	7	the bump connector being larger than the bonding area, e.g. bond pad	<administrative transfer to H10W 72/07252 and H10W 72/221 simultaneously>
D	H01L2224/16014	7	the bump connector being smaller than the bonding area, e.g. bond pad	<administrative transfer to H10W 72/07252 and

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				H10W 72/221 simultaneously >
D	H01L2224/1605	5	Shape	<administrative transfer to H10W 72/07253 and H10W 72/231 simultaneously >
D	H01L2224/16052	6	in top view	<administrative transfer to H10W 72/07253 and H10W 72/232 simultaneously>
D	H01L2224/16054	7	being rectangular or square	<administrative transfer to H10W 72/07253 and H10W 72/232 simultaneously>
D	H01L2224/16055	7	being circular or elliptic	<administrative transfer to H10W 72/07253 and H10W 72/232 simultaneously>
D	H01L2224/16056	7	comprising protrusions or indentations	<administrative transfer to H10W 72/07253 and H10W 72/232 simultaneously>
D	H01L2224/16057	6	in side view	<administrative transfer to H10W 72/07253 and H10W 72/234 simultaneously>
D	H01L2224/16058	7	being non uniform along the bump connector	<administrative transfer to H10W 72/07253 and H10W 72/234 simultaneously>
D	H01L2224/16059	7	comprising protrusions or indentations	<administrative transfer to H10W 72/07253 and H10W 72/234 simultaneously>
D	H01L2224/1607	6	of bonding interfaces, e.g. interlocking features	<administrative transfer to H10W 72/07253 and H10W 72/234 simultaneously>
D	H01L2224/161	5	Disposition	<administrative transfer to H10W 72/07254 and H10W 72/241 simultaneously>
D	H01L2224/16104	6	relative to the bonding area, e.g. bond pad	<administrative transfer to H10W 72/07254 and H10W 72/244 simultaneously>
D	H01L2224/16105	7	the bump connector connecting bonding areas being not aligned with respect to each other	<administrative transfer to H10W 72/07254 and H10W 72/244 simultaneously>

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D	H01L2224/16106	7	the bump connector connecting one bonding area to at least two respective bonding areas	<administrative transfer to H10W 72/07254 and H10W 72/244 simultaneously>
D	H01L2224/16108	6	the bump connector not being orthogonal to the surface	<administrative transfer to H10W 72/07254 and H10W 72/242 simultaneously>
D	H01L2224/16111	6	the bump connector being disposed in a recess of the surface	<administrative transfer to H10W 72/07254 and H10W 72/242 simultaneously>
D	H01L2224/16112	6	the bump connector being at least partially embedded in the surface	<administrative transfer to H10W 72/07254 and H10W 72/242 simultaneously>
D	H01L2224/16113	6	the whole bump connector protruding from the surface	<administrative transfer to H10W 72/07254 and H10W 72/242 simultaneously>
D	H01L2224/1613	6	the bump connector connecting within a semiconductor or solid-state body, i.e. connecting two bonding areas on the same semiconductor or solid-state body	<administrative transfer to H10W 72/07254 and H10W 72/242 simultaneously>
D	H01L2224/16135	6	the bump connector connecting between different semiconductor or solid-state bodies, i.e. chip-to-chip	<administrative transfer to H10W 90/721>
D	H01L2224/16137	7	the bodies being arranged next to each other, e.g. on a common substrate	<administrative transfer to H10W 90/723>
D	H01L2224/16141	7	the bodies being arranged on opposite sides of a substrate, e.g. mirror arrangements	<administrative transfer to H10W 90/721>
D	H01L2224/16145	7	the bodies being stacked	<administrative transfer to H10W 90/722>
D	H01L2224/16146	8	the bump connector connecting to a via connection in the semiconductor or solid-state body	<administrative transfer to H10W 90/722>
D	H01L2224/16147	8	the bump connector connecting to a bonding area disposed in a recess of the surface	<administrative transfer to H10W 90/722>
D	H01L2224/16148	8	the bump connector connecting to a bonding area protruding from the surface	<administrative transfer to H10W 90/722>
D	H01L2224/16151	6	the bump connector connecting between a semiconductor or solid-state body and an item not being a semiconductor or solid-state body, e.g. chip-to-substrate, chip-to-passive	<administrative transfer to H10W 90/721>
D	H01L2224/16153	7	the body and the item being arranged next to each other, e.g. on a common substrate	<administrative transfer to H10W 90/721>
D	H01L2224/16155	8	the item being non-metallic, e.g. being an insulating substrate with or without metallisation	<administrative transfer to H10W 90/725>

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D	H01L2224/16157	9	the bump connector connecting to a bond pad of the item	<administrative transfer to H10W 90/725>
D	H01L2224/1616	9	the bump connector connecting to a pin of the item	<administrative transfer to H10W 90/725>
D	H01L2224/16163	9	the bump connector connecting to a potential ring of the item	<administrative transfer to H10W 90/725>
D	H01L2224/16165	9	the bump connector connecting to a via metallisation of the item	<administrative transfer to H10W 90/725>
D	H01L2224/16167	9	the bump connector connecting to a bonding area disposed in a recess of the surface of the item	<administrative transfer to H10W 90/725>
D	H01L2224/16168	9	the bump connector connecting to a bonding area protruding from the surface of the item	<administrative transfer to H10W 90/725>
D	H01L2224/16175	8	the item being metallic	<administrative transfer to H10W 90/727>
D	H01L2224/16183	9	the bump connector connecting to a potential ring of the item	<administrative transfer to H10W 90/727>
D	H01L2224/16187	9	the bump connector connecting to a bonding area disposed in a recess of the surface of the item	<administrative transfer to H10W 90/727>
D	H01L2224/16188	9	the bump connector connecting to a bonding area protruding from the surface of the item	<administrative transfer to H10W 90/727>
D	H01L2224/16195	8	the item being a discrete passive component	<administrative transfer to H10W 90/729>
D	H01L2224/16197	9	the bump connector connecting to a bonding area disposed in a recess of the surface of the item	<administrative transfer to H10W 90/729>
D	H01L2224/16198	9	the bump connector connecting to a bonding area protruding from the surface of the item	<administrative transfer to H10W 90/729>
D	H01L2224/16221	7	the body and the item being stacked	<administrative transfer to H10W 90/721>
D	H01L2224/16225	8	the item being non-metallic, e.g. insulating substrate with or without metallisation	<administrative transfer to H10W 90/724>
D	H01L2224/16227	9	the bump connector connecting to a bond pad of the item	<administrative transfer to H10W 90/724>
D	H01L2224/1623	9	the bump connector connecting to a pin of the item	<administrative transfer to H10W 90/724>
D	H01L2224/16233	9	the bump connector connecting to a potential ring of the item	<administrative transfer to H10W 90/724>
D	H01L2224/16235	9	the bump connector connecting to a via metallisation of the item	<administrative transfer to H10W 90/724>
D	H01L2224/16237	9	the bump connector connecting to a bonding area disposed in a recess of the surface of the item	<administrative transfer to H10W 90/724>
D	H01L2224/16238	9	the bump connector connecting to a bonding area protruding from the surface of the item	<administrative transfer to H10W 90/724>

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D	H01L2224/1624	9	the bump connector connecting between the body and an opposite side of the item with respect to the body	<administrative transfer to H10W 90/724>
D	H01L2224/16245	8	the item being metallic	<administrative transfer to H10W 90/726>
D	H01L2224/16253	9	the bump connector connecting to a potential ring of the item	<administrative transfer to H10W 90/726>
D	H01L2224/16257	9	the bump connector connecting to a bonding area disposed in a recess of the surface of the item	<administrative transfer to H10W 90/726>
D	H01L2224/16258	9	the bump connector connecting to a bonding area protruding from the surface of the item	<administrative transfer to H10W 90/726>
D	H01L2224/1626	9	the bump connector connecting between the body and an opposite side of the item with respect to the body	<administrative transfer to H10W 90/726>
D	H01L2224/16265	8	the item being a discrete passive component	<administrative transfer to H10W 90/728>
D	H01L2224/16267	9	the bump connector connecting to a bonding area disposed in a recess of the surface of the item	<administrative transfer to H10W 90/728>
D	H01L2224/16268	9	the bump connector connecting to a bonding area protruding from the surface of the item	<administrative transfer to H10W 90/728>
D	H01L2224/165	5	Material	<administrative transfer to H10W 72/07255 and H10W 72/251 simultaneously>
D	H01L2224/16501	6	at the bonding interface	<administrative transfer to H10W 72/07255 and H10W 72/251 simultaneously>
D	H01L2224/16502	7	comprising an eutectic alloy	<administrative transfer to H10W 72/07255 and H10W 72/2524 simultaneously>
D	H01L2224/16503	7	comprising an intermetallic compound	<administrative transfer to H10W 72/07255 and H10W 72/2528 simultaneously>
D	H01L2224/16505	6	outside the bonding interface, e.g. in the bulk of the bump connector	<administrative transfer to H10W 72/07255 and H10W 72/251 simultaneously>
D	H01L2224/16506	7	comprising an eutectic alloy	<administrative transfer to H10W 72/07255 and H10W 72/2524 simultaneously>
D	H01L2224/16507	7	comprising an intermetallic compound	<administrative transfer to H10W 72/07255 and H10W 72/2528 simultaneously>

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D	H01L2224/17	4	of a plurality of bump connectors	<administrative transfer to H10W 72/07251 and H10W 72/20 simultaneously>
D	H01L2224/1701	5	Structure	<administrative transfer to H10W 72/07252 and H10W 72/228 simultaneously>
D	H01L2224/1703	6	Bump connectors having different sizes, e.g. different diameters, heights or widths	<administrative transfer to H10W 72/07252 and H10W 72/227 simultaneously>
D	H01L2224/1705	5	Shape	<administrative transfer to H10W 72/231 and H10W 72/07253 simultaneously>
D	H01L2224/17051	6	Bump connectors having different shapes	<administrative transfer to H10W 72/237 and H10W 72/07253 simultaneously>
D	H01L2224/17055	7	of their bonding interfaces	<administrative transfer to H10W 72/237 and H10W 72/07253 simultaneously>
D	H01L2224/171	5	Disposition	<administrative transfer to H10W 72/07254 and H10W 72/247 simultaneously>
D	H01L2224/17104	6	relative to the bonding areas, e.g. bond pads	<administrative transfer to H10W 72/07254, H10W 72/244 and H10W 72/247 simultaneously>
D	H01L2224/17106	7	the bump connectors being bonded to at least one common bonding area	<administrative transfer to H10W 72/07254, H10W 72/244 and H10W 72/247 simultaneously>
D	H01L2224/17107	8	the bump connectors connecting two common bonding areas	<administrative transfer to H10W 72/07254, H10W 72/244 and H10W 72/247 simultaneously>
D	H01L2224/1712	6	Layout	<administrative transfer to H10W 72/07254 and H10W 72/248 simultaneously>
D	H01L2224/1713	7	Square or rectangular array	<administrative transfer to H10W 72/07254 and H10W 72/248 simultaneously>
D	H01L2224/17132	8	being non uniform, i.e. having a non uniform pitch across the array	<administrative transfer to H10W 72/07254 and

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				H10W 72/248 simultaneously>
D	H01L2224/17133	8	with a staggered arrangement, e.g. depopulated array	<administrative transfer to H10W 72/07254 and H10W 72/248 simultaneously>
D	H01L2224/17134	8	covering only portions of the surface to be connected	<administrative transfer to H10W 72/07254 and H10W 72/248 simultaneously>
D	H01L2224/17135	9	Covering only the peripheral area of the surface to be connected, i.e. peripheral arrangements	<administrative transfer to H10W 72/07254 and H10W 72/248 simultaneously>
D	H01L2224/17136	9	Covering only the central area of the surface to be connected, i.e. central arrangements	<administrative transfer to H10W 72/07254 and H10W 72/248 simultaneously>
D	H01L2224/1714	7	Circular array, i.e. array with radial symmetry	<administrative transfer to H10W 72/07254 and H10W 72/248 simultaneously>
D	H01L2224/17142	8	being non uniform, i.e. having a non uniform pitch across the array	<administrative transfer to H10W 72/07254 and H10W 72/248 simultaneously>
D	H01L2224/17143	8	with a staggered arrangement	<administrative transfer to H10W 72/07254 and H10W 72/248 simultaneously>
D	H01L2224/17144	8	covering only portions of the surface to be connected	<administrative transfer to H10W 72/07254 and H10W 72/248 simultaneously>
D	H01L2224/17145	9	Covering only the peripheral area of the surface to be connected, i.e. peripheral arrangements	<administrative transfer to H10W 72/07254 and H10W 72/248 simultaneously>
D	H01L2224/17146	9	Covering only the central area of the surface to be connected, i.e. central arrangements	<administrative transfer to H10W 72/07254 and H10W 72/248 simultaneously>
D	H01L2224/1715	7	Mirror array, i.e. array having only a reflection symmetry, i.e. bilateral symmetry	<administrative transfer to H10W 72/07254 and H10W 72/248 simultaneously>
D	H01L2224/17151	8	being uniform, i.e. having a uniform pitch across the array	<administrative transfer to H10W 72/07254 and H10W 72/248 simultaneously>

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D	H01L2224/17152	8	being non uniform, i.e. having a non uniform pitch across the array	<administrative transfer to H10W 72/07254 and H10W 72/248 simultaneously>
D	H01L2224/17153	8	with a staggered arrangement, e.g. depopulated array	<administrative transfer to H10W 72/07254 and H10W 72/248 simultaneously>
D	H01L2224/17154	8	covering only portions of the surface to be connected	<administrative transfer to H10W 72/07254 and H10W 72/248 simultaneously>
D	H01L2224/17155	9	Covering only the peripheral area of the surface to be connected, i.e. peripheral arrangements	<administrative transfer to H10W 72/07254 and H10W 72/248 simultaneously>
D	H01L2224/17156	9	Covering only the central area of the surface to be connected, i.e. central arrangements	<administrative transfer to H10W 72/07254 and H10W 72/248 simultaneously>
D	H01L2224/1716	7	Random layout, i.e. layout with no symmetry	<administrative transfer to H10W 72/07254 and H10W 72/248 simultaneously>
D	H01L2224/17163	8	with a staggered arrangement	<administrative transfer to H10W 72/07254 and H10W 72/248 simultaneously>
D	H01L2224/17164	8	covering only portions of the surface to be connected	<administrative transfer to H10W 72/07254 and H10W 72/248 simultaneously>
D	H01L2224/17165	9	Covering only the peripheral area of the surface to be connected, i.e. peripheral arrangements	<administrative transfer to H10W 72/07254 and H10W 72/248 simultaneously>
D	H01L2224/17166	9	Covering only the central area of the surface to be connected, i.e. central arrangements	<administrative transfer to H10W 72/07254 and H10W 72/248 simultaneously>
D	H01L2224/17177	7	Combinations of arrays with different layouts	<administrative transfer to H10W 72/07254 and H10W 72/248 simultaneously>
D	H01L2224/17179	7	Corner adaptations, i.e. disposition of the bump connectors at the corners of the semiconductor or solid-state body	<administrative transfer to H10W 72/07254 and H10W 72/248 simultaneously>
D	H01L2224/1718	6	being disposed on at least two different sides of the body, e.g. dual array	<administrative transfer to H10W 72/07254 and

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				H10W 72/247 simultaneously>
D	H01L2224/17181	7	On opposite sides of the body	<administrative transfer to H10W 72/07254 and H10W 72/247 simultaneously>
D	H01L2224/17183	7	On contiguous sides of the body	<administrative transfer to H10W 72/07254 and H10W 72/247 simultaneously>
D	H01L2224/175	5	Material	<administrative transfer to H10W 72/07255 and H10W 72/257 simultaneously>
D	H01L2224/17505	6	Bump connectors having different materials	<administrative transfer to H10W 72/07255 and H10W 72/257 simultaneously>
D	H01L2224/1751	5	Function	<administrative transfer to H10W 72/261>
D	H01L2224/17515	6	Bump connectors having different functions	<administrative transfer to H10W 72/267>
D	H01L2224/17517	7	including bump connectors providing primarily mechanical support	<administrative transfer to H10W 72/267 and H10W 72/263 simultaneously>
D	H01L2224/17519	7	including bump connectors providing primarily thermal dissipation	<administrative transfer to H10W 72/267 and H10W 72/265 simultaneously>
D	H01L2224/18	2	High density interconnect[HDI] connectors; Manufacturing methods related thereto	<administrative transfer to H10W 70/60>
D	H01L2224/19	3	Manufacturing methods of high density interconnect preforms	<administrative transfer to H10W 70/09>
D	H01L2224/20	3	Structure, shape, material or disposition of high density interconnect preforms	<administrative transfer to H10W 70/60>
D	H01L2224/21	4	of an individual HDI interconnect	<administrative transfer to H10W 70/60>
D	H01L2224/2101	5	Structure	<administrative transfer to H10W 70/60>
D	H01L2224/2105	5	Shape	<administrative transfer to H10W 70/60>
D	H01L2224/211	5	Disposition	<administrative transfer to H10W 70/60>
D	H01L2224/214	5	Connecting portions	<administrative transfer to H10W 70/6528>
D	H01L2224/215	5	Material	<administrative transfer to H10W 70/60>

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D	H01L2224/22	4	of a plurality of HDI interconnects	<administrative transfer to H10W 70/60>
D	H01L2224/2201	5	Structure	<administrative transfer to H10W 70/60>
D	H01L2224/2205	5	Shape	<administrative transfer to H10W 70/60>
D	H01L2224/221	5	Disposition	<administrative transfer to H10W 70/60>
D	H01L2224/224	5	Connecting portions	<administrative transfer to H10W 70/6528>
D	H01L2224/225	5	Material	<administrative transfer to H10W 70/60>
D	H01L2224/22505	6	HDI interconnects having different materials	<administrative transfer to H10W 70/60>
D	H01L2224/23	3	Structure, shape, material or disposition of the high density interconnect connectors after the connecting process	<administrative transfer to H10W 70/60>
D	H01L2224/24	4	of an individual high density interconnect connector	<administrative transfer to H10W 70/60>
D	H01L2224/2401	5	Structure	<administrative transfer to H10W 70/60>
D	H01L2224/24011	6	Deposited, e.g. MCM-D type	<administrative transfer to H10W 70/60>
D	H01L2224/2402	6	Laminated, e.g. MCM-L type	<administrative transfer to H10W 70/60>
D	H01L2224/2405	5	Shape	<administrative transfer to H10W 70/60>
D	H01L2224/24051	6	Conformal with the semiconductor or solid-state device	<administrative transfer to H10W 70/60>
D	H01L2224/241	5	Disposition	<administrative transfer to H10W 70/60>
D	H01L2224/24101	6	Connecting bonding areas at the same height	<administrative transfer to H10W 70/60>
D	H01L2224/24105	6	Connecting bonding areas at different heights	<administrative transfer to H10W 70/6523>
D	H01L2224/2413	6	Connecting within a semiconductor or solid-state body	<administrative transfer to H10W 70/60>
D	H01L2224/24135	6	Connecting between different semiconductor or solid-state bodies, i.e. chip-to-chip	<administrative transfer to H10W 90/00>
D	H01L2224/24137	7	the bodies being arranged next to each other, e.g. on a common substrate	<administrative transfer to H10W 90/10>
D	H01L2224/24141	7	the bodies being arranged on opposite sides of a substrate, e.g. mirror arrangements	<administrative transfer to H10W 90/20>
D	H01L2224/24145	7	the bodies being stacked	<administrative transfer to H10W 90/22>
D	H01L2224/24146	8	the HDI interconnect connecting to the same level of the lower semiconductor or solid-	<administrative transfer to H10W 90/22>

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			state body at which the upper semiconductor or solid-state body is mounted	
D	H01L2224/24147	8	the HDI interconnect not connecting to the same level of the lower semiconductor or solid-state body at which the upper semiconductor or solid-state body is mounted, e.g. the upper semiconductor or solid-state body being mounted in a cavity or on a protrusion of the lower semiconductor or solid-state body	<administrative transfer to H10W 90/22>
D	H01L2224/24151	6	Connecting between a semiconductor or solid-state body and an item not being a semiconductor or solid-state body, e.g. chip-to-substrate, chip-to-passive	<administrative transfer to H10W 90/00>
D	H01L2224/24153	7	the body and the item being arranged next to each other, e.g. on a common substrate	<administrative transfer to H10W 90/00>
D	H01L2224/24155	8	the item being non-metallic, e.g. insulating substrate with or without metallisation	<administrative transfer to H10W 90/00>
D	H01L2224/24175	8	the item being metallic	<administrative transfer to H10W 90/00>
D	H01L2224/24195	8	the item being a discrete passive component	<administrative transfer to H10W 90/00>
D	H01L2224/24221	7	the body and the item being stacked	<administrative transfer to H10W 90/00>
D	H01L2224/24225	8	the item being non-metallic, e.g. insulating substrate with or without metallisation	<administrative transfer to H10W 90/00>
D	H01L2224/24226	9	the HDI interconnect connecting to the same level of the item at which the semiconductor or solid-state body is mounted, e.g. the item being planar	<administrative transfer to H10W 90/00>
D	H01L2224/24227	9	the HDI interconnect not connecting to the same level of the item at which the semiconductor or solid-state body is mounted, e.g. the semiconductor or solid-state body being mounted in a cavity or on a protrusion of the item	<administrative transfer to H10W 90/00>
D	H01L2224/24245	8	the item being metallic	<administrative transfer to H10W 90/00>
D	H01L2224/24246	9	the HDI interconnect connecting to the same level of the item at which the semiconductor or solid-state body is mounted, e.g. the item being planar	<administrative transfer to H10W 90/00>
D	H01L2224/24247	9	the HDI interconnect not connecting to the same level of the item at which the semiconductor or solid-state body is mounted, e.g. the semiconductor or solid-state body being mounted in a cavity or on a protrusion of the item	<administrative transfer to H10W 90/00>

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D	H01L2224/24265	8	the item being a discrete passive component	<administrative transfer to H10W 90/00>
D	H01L2224/244	5	Connecting portions	<administrative transfer to H10W 70/6528>
D	H01L2224/245	5	Material	<administrative transfer to H10W 70/60>
D	H01L2224/2499	5	Auxiliary members for HDI interconnects, e.g. spacers, alignment aids	<administrative transfer to H10W 70/60>
D	H01L2224/24991	6	being formed on the semiconductor or solid-state body to be connected	<administrative transfer to H10W 70/60>
D	H01L2224/24992	7	Flow barrier	<administrative transfer to H10W 70/60>
D	H01L2224/24996	6	being formed on an item to be connected not being a semiconductor or solid-state body	<administrative transfer to H10W 70/60>
D	H01L2224/24997	7	Flow barrier	<administrative transfer to H10W 70/60>
D	H01L2224/24998	7	Reinforcing structures, e.g. ramp-like support	<administrative transfer to H10W 70/60>
D	H01L2224/25	4	of a plurality of high density interconnect connectors	<administrative transfer to H10W 70/60>
D	H01L2224/2501	5	Structure	<administrative transfer to H10W 70/60>
D	H01L2224/2505	5	Shape	<administrative transfer to H10W 70/60>
D	H01L2224/251	5	Disposition	<administrative transfer to H10W 70/60>
D	H01L2224/25105	6	Connecting at different heights	<administrative transfer to H10W 70/6523>
D	H01L2224/2511	6	the connectors being bonded to at least one common bonding area	<administrative transfer to H10W 70/60>
D	H01L2224/25111	7	the connectors connecting two common bonding areas	<administrative transfer to H10W 70/60>
D	H01L2224/25112	7	the connectors connecting a common bonding area on the semiconductor or solid-state body to different bonding areas outside the body	<administrative transfer to H10W 70/60>
D	H01L2224/25113	7	the connectors connecting different bonding areas on the semiconductor or solid-state body to a common bonding area outside the body	<administrative transfer to H10W 70/60>
D	H01L2224/2512	6	Layout	<administrative transfer to H10W 70/654>
D	H01L2224/25171	7	Fan-out arrangements	<administrative transfer to H10W 70/655>
D	H01L2224/25174	7	Stacked arrangements	<administrative transfer to H10W 70/654>
D	H01L2224/25175	7	Parallel arrangements	<administrative transfer to H10W 70/654>

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D	H01L2224/25177	7	Combinations of a plurality of arrangements	<administrative transfer to H10W 70/654>
D	H01L2224/2518	6	being disposed on at least two different sides of the body, e.g. dual array	<administrative transfer to H10W 70/60>
D	H01L2224/254	5	Connecting portions	<administrative transfer to H10W 70/6528>
D	H01L2224/2541	6	the connecting portions being stacked	<administrative transfer to H10W 70/6528>
D	H01L2224/2543	6	the connecting portions being staggered	<administrative transfer to H10W 70/6528>
D	H01L2224/255	5	Material	<administrative transfer to H10W 70/65>
D	H01L2224/26	2	Layer connectors, e.g. plate connectors, solder or adhesive layers; Manufacturing methods related thereto	<administrative transfer to H10W 72/30>
D	H01L2224/2612	3	Auxiliary members for layer connectors, e.g. spacers	<administrative transfer to H10W 72/381>
D	H01L2224/26122	4	being formed on the semiconductor or solid-state body to be connected	<administrative transfer to H10W 72/381>
D	H01L2224/26125	5	Reinforcing structures	<administrative transfer to H10W 72/383>
D	H01L2224/26135	5	Alignment aids	<administrative transfer to H10W 72/385>
D	H01L2224/26145	5	Flow barriers	<administrative transfer to H10W 72/387>
D	H01L2224/26152	4	being formed on an item to be connected not being a semiconductor or solid-state body	<administrative transfer to H10W 72/381>
D	H01L2224/26155	5	Reinforcing structures	<administrative transfer to H10W 72/383>
D	H01L2224/26165	5	Alignment aids	<administrative transfer to H10W 72/385>
D	H01L2224/26175	5	Flow barriers	<administrative transfer to H10W 72/387>
D	H01L2224/27	3	Manufacturing methods	<administrative transfer to H10W 72/013>
D	H01L2224/27001	4	Involving a temporary auxiliary member not forming part of the manufacturing apparatus, e.g. removable or sacrificial coating, film or substrate	<administrative transfer to H10W 72/01304>
D	H01L2224/27002	5	for supporting the semiconductor or solid-state body	<administrative transfer to H10W 72/01304>
D	H01L2224/27003	5	for holding or transferring the layer preform	<administrative transfer to H10W 72/01304>
D	H01L2224/27005	5	for aligning the layer connector, e.g. marks, spacers	<administrative transfer to H10W 72/01304>
D	H01L2224/27009	5	for protecting parts during manufacture	<administrative transfer to H10W 72/01304>

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D	H01L2224/27011	4	Involving a permanent auxiliary member, i.e. a member which is left at least partly in the finished device, e.g. coating, dummy feature	<administrative transfer to H10W 72/01308>
D	H01L2224/27013	5	for holding or confining the layer connector, e.g. solder flow barrier	<administrative transfer to H10W 72/01308>
D	H01L2224/27015	5	for aligning the layer connector, e.g. marks, spacers	<administrative transfer to H10W 72/01308>
D	H01L2224/27019	5	for protecting parts during the process	<administrative transfer to H10W 72/01308>
D	H01L2224/271	4	Manufacture and pre-treatment of the layer connector preform	<administrative transfer to H10W 72/013>
D	H01L2224/2711	5	Shaping	<administrative transfer to H10W 72/01351>
D	H01L2224/2712	5	Applying permanent coating	<administrative transfer to H10W 72/01315>
D	H01L2224/273	4	by local deposition of the material of the layer connector	<administrative transfer to H10W 72/01321>
D	H01L2224/2731	5	in liquid form	<administrative transfer to H10W 72/01323>
D	H01L2224/27312	6	Continuous flow, e.g. using a microsyringe, a pump, a nozzle or extrusion	<administrative transfer to H10W 72/01323>
D	H01L2224/27318	6	by dispensing droplets	<administrative transfer to H10W 72/01323>
D	H01L2224/2732	6	Screen printing, i.e. using a stencil	<administrative transfer to H10W 72/01323>
D	H01L2224/2733	5	in solid form	<administrative transfer to H10W 72/01325>
D	H01L2224/27332	6	using a powder	<administrative transfer to H10W 72/01325>
D	H01L2224/27334	6	using preformed layer	<administrative transfer to H10W 72/01325>
D	H01L2224/274	4	by blanket deposition of the material of the layer connector	<administrative transfer to H10W 72/01331>
D	H01L2224/2741	5	in liquid form	<administrative transfer to H10W 72/01333>
D	H01L2224/27416	6	Spin coating	<administrative transfer to H10W 72/01333>
D	H01L2224/27418	6	Spray coating	<administrative transfer to H10W 72/01333>
D	H01L2224/2742	6	Curtain coating	<administrative transfer to H10W 72/01333>
D	H01L2224/27422	6	by dipping, e.g. in a solder bath	<administrative transfer to H10W 72/01333>
D	H01L2224/27424	6	Immersion coating, e.g. in a solder bath	<administrative transfer to H10W 72/01333>
D	H01L2224/27426	6	Chemical solution deposition [CSD], i.e. using a liquid precursor	<administrative transfer to H10W 72/01333>

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D	H01L2224/27428	6	Wave coating	<administrative transfer to H10W 72/01333>
D	H01L2224/2743	5	in solid form	<administrative transfer to H10W 72/01336>
D	H01L2224/27436	6	Lamination of a preform, e.g. foil, sheet or layer	<administrative transfer to H10W 72/01336>
D	H01L2224/27438	7	the preform being at least partly pre-pattered	<administrative transfer to H10W 72/01336>
D	H01L2224/2744	7	by transfer printing	<administrative transfer to H10W 72/01336>
D	H01L2224/27442	6	using a powder	<administrative transfer to H10W 72/01336>
D	H01L2224/27444	5	in gaseous form	<administrative transfer to H10W 72/01338>
D	H01L2224/2745	6	Physical vapour deposition [PVD], e.g. evaporation, or sputtering	<administrative transfer to H10W 72/01338>
D	H01L2224/27452	6	Chemical vapour deposition [CVD], e.g. laser CVD	<administrative transfer to H10W 72/01338>
D	H01L2224/2746	5	Plating	<administrative transfer to H10W 72/01335>
D	H01L2224/27462	6	Electroplating	<administrative transfer to H10W 72/01335>
D	H01L2224/27464	6	Electroless plating	<administrative transfer to H10W 72/01335>
D	H01L2224/27466	5	Conformal deposition, i.e. blanket deposition of a conformal layer on a patterned surface	<administrative transfer to H10W 72/01331>
D	H01L2224/2747	4	using a lift-off mask	<administrative transfer to H10W 72/013>
D	H01L2224/27472	5	Profile of the lift-off mask	<administrative transfer to H10W 72/013>
D	H01L2224/27474	5	Multilayer masks	<administrative transfer to H10W 72/013>
D	H01L2224/2748	5	Permanent masks, i.e. masks left in the finished device, e.g. passivation layers	<administrative transfer to H10W 72/013>
D	H01L2224/275	4	by chemical or physical modification of a pre-existing or pre-deposited material	<administrative transfer to H10W 72/01361>
D	H01L2224/27502	5	Pre-existing or pre-deposited material	<administrative transfer to H10W 72/01361>
D	H01L2224/27505	5	Sintering	<administrative transfer to H10W 72/01361>
D	H01L2224/2751	5	Anodisation	<administrative transfer to H10W 72/01361>
D	H01L2224/27515	5	Curing and solidification, e.g. of a photosensitive layer material	<administrative transfer to H10W 72/01361>
D	H01L2224/2752	5	Self-assembly, e.g. self-agglomeration of the layer material in a fluid	<administrative transfer to H10W 72/01361>
D	H01L2224/27522	6	Auxiliary means therefor, e.g. for self-assembly activation	<administrative transfer to H10W 72/01361>

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D	H01L2224/27524	6	with special adaptation of the surface or of an auxiliary substrate, e.g. surface shape specially adapted for the self-assembly process	<administrative transfer to H10W 72/01361>
D	H01L2224/27526	6	involving the material of the bonding area, e.g. bonding pad	<administrative transfer to H10W 72/01361>
D	H01L2224/2755	5	Selective modification	<administrative transfer to H10W 72/01361>
D	H01L2224/27552	6	using a laser or a focussed ion beam [FIB]	<administrative transfer to H10W 72/01361>
D	H01L2224/27554	7	Stereolithography, i.e. solidification of a pattern defined by a laser trace in a photosensitive resin	<administrative transfer to H10W 72/01361>
D	H01L2224/276	4	by patterning a pre-deposited material	<administrative transfer to H10W 72/01351>
D	H01L2224/27602	5	Mechanical treatment, e.g. polishing, grinding	<administrative transfer to H10W 72/01351>
D	H01L2224/2761	5	Physical or chemical etching	<administrative transfer to H10W 72/01353>
D	H01L2224/27612	6	by physical means only	<administrative transfer to H10W 72/01353>
D	H01L2224/27614	6	by chemical means only	<administrative transfer to H10W 72/01353>
D	H01L2224/27616	6	Chemical mechanical polishing [CMP]	<administrative transfer to H10W 72/01353>
D	H01L2224/27618	5	with selective exposure, development and removal of a photosensitive layer material, e.g. of a photosensitive conductive resin	<administrative transfer to H10W 72/01351>
D	H01L2224/2762	5	using masks	<administrative transfer to H10W 72/01355>
D	H01L2224/27622	6	Photolithography	<administrative transfer to H10W 72/01355>
D	H01L2224/2763	5	using a laser or a focused ion beam [FIB]	<administrative transfer to H10W 72/01351>
D	H01L2224/27632	6	Ablation by means of a laser or focused ion beam [FIB]	<administrative transfer to H10W 72/01351>
D	H01L2224/277	4	involving monitoring, e.g. feedback loop	<administrative transfer to H10W 72/013>
D	H01L2224/278	4	Post-treatment of the layer connector	<administrative transfer to H10W 72/013>
D	H01L2224/2781	5	Cleaning, e.g. oxide removal step, desmearing	<administrative transfer to H10W 72/01371>
D	H01L2224/2782	5	Applying permanent coating, e.g. in-situ coating	<administrative transfer to H10W 72/01315>
D	H01L2224/27821	6	Spray coating	<administrative transfer to H10W 72/01315>
D	H01L2224/27822	6	by dipping, e.g. in a solder bath	<administrative transfer to H10W 72/01315>

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D	H01L2224/27823	6	Immersion coating, e.g. in a solder bath	<administrative transfer to H10W 72/01315>
D	H01L2224/27824	6	Chemical solution deposition [CSD], i.e. using a liquid precursor	<administrative transfer to H10W 72/01315>
D	H01L2224/27825	6	Plating, e.g. electroplating, electroless plating	<administrative transfer to H10W 72/01315>
D	H01L2224/27826	6	Physical vapour deposition [PVD], e.g. evaporation, or sputtering	<administrative transfer to H10W 72/01315>
D	H01L2224/27827	6	Chemical vapour deposition [CVD], e.g. laser CVD	<administrative transfer to H10W 72/01315>
D	H01L2224/2783	5	Reworking, e.g. shaping	<administrative transfer to H10W 72/01351>
D	H01L2224/27831	6	involving a chemical process, e.g. etching the layer connector	<administrative transfer to H10W 72/01353>
D	H01L2224/2784	6	involving a mechanical process, e.g. planarising the layer connector	<administrative transfer to H10W 72/01351>
D	H01L2224/27845	6	Chemical mechanical polishing [CMP]	<administrative transfer to H10W 72/01359>
D	H01L2224/27848	5	Thermal treatments, e.g. annealing, controlled cooling	<administrative transfer to H10W 72/01365>
D	H01L2224/27849	6	Reflowing	<administrative transfer to H10W 72/01357>
D	H01L2224/279	4	Methods of manufacturing layer connectors involving a specific sequence of method steps	<administrative transfer to H10W 72/013>
D	H01L2224/27901	5	with repetition of the same manufacturing step	<administrative transfer to H10W 72/013>
D	H01L2224/27902	6	Multiple masking steps	<administrative transfer to H10W 72/013>
D	H01L2224/27903	7	using different masks	<administrative transfer to H10W 72/013>
D	H01L2224/27906	7	with modification of the same mask	<administrative transfer to H10W 72/013>
D	H01L2224/2791	5	Forming a passivation layer after forming the layer connector	<administrative transfer to H10W 72/013>
D	H01L2224/27912	5	the layer being used as a mask for patterning other parts	<administrative transfer to H10W 72/013>
D	H01L2224/27916	5	a passivation layer being used as a mask for patterning other parts	<administrative transfer to H10W 72/013>
D	H01L2224/28	3	Structure, shape, material or disposition of the layer connectors prior to the connecting process	<administrative transfer to H10W 72/30>
D	H01L2224/28105	4	Layer connectors formed on an encapsulation of the semiconductor or solid-state body, e.g. layer connectors on chip-scale packages	<administrative transfer to H10W 72/341>
D	H01L2224/29	4	of an individual layer connector	<administrative transfer to H10W 72/30>
D	H01L2224/29001	5	Core members of the layer connector	<administrative transfer to H10W 72/30>

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D	H01L2224/29005	6	Structure	<administrative transfer to H10W 72/321>
D	H01L2224/29006	7	Layer connector larger than the underlying bonding area	<administrative transfer to H10W 72/321>
D	H01L2224/29007	7	Layer connector smaller than the underlying bonding area	<administrative transfer to H10W 72/321>
D	H01L2224/29008	7	Layer connector integrally formed with a redistribution layer on the semiconductor or solid-state body	<administrative transfer to H10W 72/321>
D	H01L2224/29009	7	Layer connector integrally formed with a via connection of the semiconductor or solid-state body	<administrative transfer to H10W 72/321>
D	H01L2224/2901	6	Shape	<administrative transfer to H10W 72/331>
D	H01L2224/29011	7	comprising apertures or cavities	<administrative transfer to H10W 72/331>
D	H01L2224/29012	7	in top view	<administrative transfer to H10W 72/332>
D	H01L2224/29013	8	being rectangular or square	<administrative transfer to H10W 72/332>
D	H01L2224/29014	8	being circular or elliptic	<administrative transfer to H10W 72/332>
D	H01L2224/29015	8	comprising protrusions or indentations	<administrative transfer to H10W 72/332>
D	H01L2224/29016	7	in side view	<administrative transfer to H10W 72/334>
D	H01L2224/29017	8	being non uniform along the layer connector	<administrative transfer to H10W 72/334>
D	H01L2224/29018	8	comprising protrusions or indentations	<administrative transfer to H10W 72/334>
D	H01L2224/29019	9	at the bonding interface of the layer connector, i.e. on the surface of the layer connector	<administrative transfer to H10W 72/334>
D	H01L2224/2902	6	Disposition	<administrative transfer to H10W 72/341>
D	H01L2224/29021	7	the layer connector being disposed in a recess of the surface	<administrative transfer to H10W 72/342>
D	H01L2224/29022	7	the layer connector being at least partially embedded in the surface	<administrative transfer to H10W 72/342>
D	H01L2224/29023	7	the whole layer connector protruding from the surface	<administrative transfer to H10W 72/342>
D	H01L2224/29024	7	the layer connector being disposed on a redistribution layer on the semiconductor or solid-state body	<administrative transfer to H10W 72/344>
D	H01L2224/29025	7	the layer connector being disposed on a via connection of the semiconductor or solid-state body	<administrative transfer to H10W 72/344>

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D	H01L2224/29026	7	relative to the bonding area, e.g. bondpad, of the semiconductor or solid-state body	<administrative transfer to H10W 72/344>
D	H01L2224/29027	8	the layer connector being offset with respect to the bonding area, e.g. bond pad	<administrative transfer to H10W 72/344>
D	H01L2224/29028	8	the layer connector being disposed on at least two separate bonding areas, e.g. bond pads	<administrative transfer to H10W 72/344>
D	H01L2224/29034	7	the layer connector covering only portions of the surface to be connected	<administrative transfer to H10W 72/344>
D	H01L2224/29035	8	covering only the peripheral area of the surface to be connected	<administrative transfer to H10W 72/344>
D	H01L2224/29036	8	covering only the central area of the surface to be connected	<administrative transfer to H10W 72/344>
D	H01L2224/29075	6	Plural core members	<administrative transfer to H10W 72/321>
D	H01L2224/29076	7	being mutually engaged together, e.g. through inserts	<administrative transfer to H10W 72/321>
D	H01L2224/29078	7	being disposed next to each other, e.g. side-to-side arrangements	<administrative transfer to H10W 72/324>
D	H01L2224/2908	7	being stacked	<administrative transfer to H10W 72/322>
D	H01L2224/29082	8	Two-layer arrangements	<administrative transfer to H10W 72/322>
D	H01L2224/29083	8	Three-layer arrangements	<administrative transfer to H10W 72/322>
D	H01L2224/29084	8	Four-layer arrangements	<administrative transfer to H10W 72/322>
D	H01L2224/29099	6	Material	<administrative transfer to H10W 72/351>
D	H01L2224/291	7	with a principal constituent of the material being a metal or a metalloid, e.g. boron [B], silicon [Si], germanium [Ge], arsenic [As], antimony [Sb], tellurium [Te] and polonium [Po], and alloys thereof	<administrative transfer to H10W 72/352>
D	H01L2224/29101	8	the principal constituent melting at a temperature of less than 400°C	<administrative transfer to H10W 72/352>
D	H01L2224/29105	9	Gallium [Ga] as principal constituent	<administrative transfer to H10W 72/352>
D	H01L2224/29109	9	Indium [In] as principal constituent	<administrative transfer to H10W 72/352>
D	H01L2224/29111	9	Tin [Sn] as principal constituent	<administrative transfer to H10W 72/352>
D	H01L2224/29113	9	Bismuth [Bi] as principal constituent	<administrative transfer to H10W 72/352>
D	H01L2224/29114	9	Thallium [Tl] as principal constituent	<administrative transfer to H10W 72/352>
D	H01L2224/29116	9	Lead [Pb] as principal constituent	<administrative transfer to H10W 72/352>

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D	H01L2224/29117	8	the principal constituent melting at a temperature of greater than or equal to 400°C and less than 950°C	<administrative transfer to H10W 72/352>
D	H01L2224/29118	9	Zinc [Zn] as principal constituent	<administrative transfer to H10W 72/352>
D	H01L2224/2912	9	Antimony [Sb] as principal constituent	<administrative transfer to H10W 72/352>
D	H01L2224/29123	9	Magnesium [Mg] as principal constituent	<administrative transfer to H10W 72/352>
D	H01L2224/29124	9	Aluminium [Al] as principal constituent	<administrative transfer to H10W 72/352>
D	H01L2224/29138	8	the principal constituent melting at a temperature of greater than or equal to 950°C and less than 1550°C	<administrative transfer to H10W 72/352>
D	H01L2224/29139	9	Silver [Ag] as principal constituent	<administrative transfer to H10W 72/352>
D	H01L2224/29144	9	Gold [Au] as principal constituent	<administrative transfer to H10W 72/352>
D	H01L2224/29147	9	Copper [Cu] as principal constituent	<administrative transfer to H10W 72/352>
D	H01L2224/29149	9	Manganese [Mn] as principal constituent	<administrative transfer to H10W 72/352>
D	H01L2224/29155	9	Nickel [Ni] as principal constituent	<administrative transfer to H10W 72/352>
D	H01L2224/29157	9	Cobalt [Co] as principal constituent	<administrative transfer to H10W 72/352>
D	H01L2224/2916	9	Iron [Fe] as principal constituent	<administrative transfer to H10W 72/352>
D	H01L2224/29163	8	the principal constituent melting at a temperature of greater than 1550°C	<administrative transfer to H10W 72/352>
D	H01L2224/29164	9	Palladium [Pd] as principal constituent	<administrative transfer to H10W 72/352>
D	H01L2224/29166	9	Titanium [Ti] as principal constituent	<administrative transfer to H10W 72/352>
D	H01L2224/29169	9	Platinum [Pt] as principal constituent	<administrative transfer to H10W 72/352>
D	H01L2224/2917	9	Zirconium [Zr] as principal constituent	<administrative transfer to H10W 72/352>
D	H01L2224/29171	9	Chromium [Cr] as principal constituent	<administrative transfer to H10W 72/352>
D	H01L2224/29172	9	Vanadium [V] as principal constituent	<administrative transfer to H10W 72/352>
D	H01L2224/29173	9	Rhodium [Rh] as principal constituent	<administrative transfer to H10W 72/352>
D	H01L2224/29176	9	Ruthenium [Ru] as principal constituent	<administrative transfer to H10W 72/352>
D	H01L2224/29178	9	Iridium [Ir] as principal constituent	<administrative transfer to H10W 72/352>

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D	H01L2224/29179	9	Niobium [Nb] as principal constituent	<administrative transfer to H10W 72/352>
D	H01L2224/2918	9	Molybdenum [Mo] as principal constituent	<administrative transfer to H10W 72/352>
D	H01L2224/29181	9	Tantalum [Ta] as principal constituent	<administrative transfer to H10W 72/352>
D	H01L2224/29183	9	Rhenium [Re] as principal constituent	<administrative transfer to H10W 72/352>
D	H01L2224/29184	9	Tungsten [W] as principal constituent	<administrative transfer to H10W 72/352>
D	H01L2224/29186	7	with a principal constituent of the material being a non metallic, non metalloid inorganic material	<administrative transfer to H10W 72/353>
D	H01L2224/29187	8	Ceramics, e.g. crystalline carbides, nitrides or oxides	<administrative transfer to H10W 72/353>
D	H01L2224/29188	8	Glasses, e.g. amorphous oxides, nitrides or fluorides	<administrative transfer to H10W 72/353>
D	H01L2224/2919	7	with a principal constituent of the material being a polymer, e.g. polyester, phenolic based polymer, epoxy	<administrative transfer to H10W 72/354>
D	H01L2224/29191	8	The principal constituent being an elastomer, e.g. silicones, isoprene, neoprene	<administrative transfer to H10W 72/354>
D	H01L2224/29193	7	with a principal constituent of the material being a solid not provided for in groups H01L2224/291 - H01L2224/29191, e.g. allotropes of carbon, fullerene, graphite, carbon-nanotubes, diamond	<administrative transfer to H10W 72/353>
D	H01L2224/29194	7	with a principal constituent of the material being a liquid not provided for in groups H01L2224/291 - H01L2224/29191	<administrative transfer to H10W 72/353>
D	H01L2224/29195	7	with a principal constituent of the material being a gas not provided for in groups H01L2224/291 - H01L2224/29191	<administrative transfer to H10W 72/353>
D	H01L2224/29198	7	with a principal constituent of the material being a combination of two or more materials in the form of a matrix with a filler, i.e. being a hybrid material, e.g. segmented structures, foams	<administrative transfer to H10W 72/325 and H10W 72/351 simultaneously>
D	H01L2224/29199	8	Material of the matrix	<administrative transfer to H10W 72/325 and H10W 72/351 simultaneously>
D	H01L2224/292	9	with a principal constituent of the material being a metal or a metalloid, e.g. boron [B], silicon [Si], germanium [Ge], arsenic [As], antimony [Sb], tellurium [Te] and polonium [Po], and alloys thereof	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29201	10	the principal constituent melting at a temperature of less than 400°C	<administrative transfer to H10W 72/325 and

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				H10W 72/352 simultaneously>
D	H01L2224/29205	11	Gallium [Ga] as principal constituent	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29209	11	Indium [In] as principal constituent	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29211	11	Tin [Sn] as principal constituent	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29213	11	Bismuth [Bi] as principal constituent	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29214	11	Thallium [Tl] as principal constituent	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29216	11	Lead [Pb] as principal constituent	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29217	10	the principal constituent melting at a temperature of greater than or equal to 400°C and less than 950°C	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29218	11	Zinc [Zn] as principal constituent	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/2922	11	Antimony [Sb] as principal constituent	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29223	11	Magnesium [Mg] as principal constituent	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29224	11	Aluminium [Al] as principal constituent	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29238	10	the principal constituent melting at a temperature of greater than or equal to 950°C and less than 1550°C	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>

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D	H01L2224/29239	11	Silver [Ag] as principal constituent	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29244	11	Gold [Au] as principal constituent	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29247	11	Copper [Cu] as principal constituent	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29249	11	Manganese [Mn] as principal constituent	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29255	11	Nickel [Ni] as principal constituent	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29257	11	Cobalt [Co] as principal constituent	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/2926	11	Iron [Fe] as principal constituent	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29263	10	the principal constituent melting at a temperature of greater than 1550°C	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29264	11	Palladium [Pd] as principal constituent	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29266	11	Titanium [Ti] as principal constituent	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29269	11	Platinum [Pt] as principal constituent	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/2927	11	Zirconium [Zr] as principal constituent	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29271	11	Chromium [Cr] as principal constituent	<administrative transfer to H10W 72/325 and

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				H10W 72/352 simultaneously>
D	H01L2224/29272	11	Vanadium [V] as principal constituent	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29273	11	Rhodium [Rh] as principal constituent	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29276	11	Ruthenium [Ru] as principal constituent	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29278	11	Iridium [Ir] as principal constituent	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29279	11	Niobium [Nb] as principal constituent	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/2928	11	Molybdenum [Mo] as principal constituent	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29281	11	Tantalum [Ta] as principal constituent	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29283	11	Rhenium [Re] as principal constituent	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29284	11	Tungsten [W] as principal constituent	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29286	9	with a principal constituent of the material being a non metallic, non metalloid inorganic material	<administrative transfer to H10W 72/325 and H10W 72/353 simultaneously>
D	H01L2224/29287	10	Ceramics, e.g. crystalline carbides, nitrides or oxides	<administrative transfer to H10W 72/325 and H10W 72/353 simultaneously>
D	H01L2224/29288	10	Glasses, e.g. amorphous oxides, nitrides or fluorides	<administrative transfer to H10W 72/325 and H10W 72/353 simultaneously>

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D	H01L2224/2929	9	with a principal constituent of the material being a polymer, e.g. polyester, phenolic based polymer, epoxy	<administrative transfer to H10W 72/325 and H10W 72/354 simultaneously>
D	H01L2224/29291	10	The principal constituent being an elastomer, e.g. silicones, isoprene, neoprene	<administrative transfer to H10W 72/325 and H10W 72/354 simultaneously>
D	H01L2224/29293	9	with a principal constituent of the material being a solid not provided for in groups H01L2224/292 - H01L2224/29291, e.g. allotropes of carbon, fullerene, graphite, carbon-nanotubes, diamond	<administrative transfer to H10W 72/325 and H10W 72/353 simultaneously>
D	H01L2224/29294	9	with a principal constituent of the material being a liquid not provided for in groups H01L2224/292 - H01L2224/29291	<administrative transfer to H10W 72/325 and H10W 72/353 simultaneously>
D	H01L2224/29295	9	with a principal constituent of the material being a gas not provided for in groups H01L2224/292 - H01L2224/29291	<administrative transfer to H10W 72/325 and H10W 72/353 simultaneously>
D	H01L2224/29298	8	Fillers	<administrative transfer to H10W 72/325 and H10W 72/351 simultaneously>
D	H01L2224/29299	9	Base material	<administrative transfer to H10W 72/325 and H10W 72/351 simultaneously>
D	H01L2224/293	10	with a principal constituent of the material being a metal or a metalloid, e.g. boron [B], silicon [Si], germanium [Ge], arsenic [As], antimony [Sb], tellurium [Te] and polonium [Po], and alloys thereof	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29301	11	the principal constituent melting at a temperature of less than 400°C	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29305	12	Gallium [Ga] as principal constituent	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29309	12	Indium [In] as principal constituent	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29311	12	Tin [Sn] as principal constituent	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>

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D	H01L2224/29313	12	Bismuth [Bi] as principal constituent	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29314	12	Thallium [Tl] as principal constituent	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29316	12	Lead [Pb] as principal constituent	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29317	11	the principal constituent melting at a temperature of greater than or equal to 400°C and less than 950°C	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29318	12	Zinc [Zn] as principal constituent	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/2932	12	Antimony [Sb] as principal constituent	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29323	12	Magnesium [Mg] as principal constituent	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29324	12	Aluminium [Al] as principal constituent	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29338	11	the principal constituent melting at a temperature of greater than or equal to 950°C and less than 1550°C	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29339	12	Silver [Ag] as principal constituent	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29344	12	Gold [Au] as principal constituent	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29347	12	Copper [Cu] as principal constituent	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29349	12	Manganese [Mn] as principal constituent	<administrative transfer to H10W 72/325 and

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				H10W 72/352 simultaneously>
D	H01L2224/29355	12	Nickel [Ni] as principal constituent	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29357	12	Cobalt [Co] as principal constituent	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/2936	12	Iron [Fe] as principal constituent	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29363	11	the principal constituent melting at a temperature of greater than 1550°C	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29364	12	Palladium [Pd] as principal constituent	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29366	12	Titanium [Ti] as principal constituent	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29369	12	Platinum [Pt] as principal constituent	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/2937	12	Zirconium [Zr] as principal constituent	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29371	12	Chromium [Cr] as principal constituent	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29372	12	Vanadium [V] as principal constituent	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29373	12	Rhodium [Rh] as principal constituent	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29376	12	Ruthenium [Ru] as principal constituent	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>

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D	H01L2224/29378	12	Iridium [Ir] as principal constituent	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29379	12	Niobium [Nb] as principal constituent	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/2938	12	Molybdenum [Mo] as principal constituent	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29381	12	Tantalum [Ta] as principal constituent	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29383	12	Rhenium [Re] as principal constituent	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29384	12	Tungsten [W] as principal constituent	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29386	10	with a principal constituent of the material being a non metallic, non metalloid inorganic material	<administrative transfer to H10W 72/325 and H10W 72/353 simultaneously>
D	H01L2224/29387	11	Ceramics, e.g. crystalline carbides, nitrides or oxides	<administrative transfer to H10W 72/325 and H10W 72/353 simultaneously>
D	H01L2224/29388	11	Glasses, e.g. amorphous oxides, nitrides or fluorides	<administrative transfer to H10W 72/325 and H10W 72/353 simultaneously>
D	H01L2224/2939	10	with a principal constituent of the material being a polymer, e.g. polyester, phenolic based polymer, epoxy	<administrative transfer to H10W 72/325 and H10W 72/354 simultaneously>
D	H01L2224/29391	11	The principal constituent being an elastomer, e.g. silicones, isoprene, neoprene	<administrative transfer to H10W 72/325 and H10W 72/354 simultaneously>
D	H01L2224/29393	10	with a principal constituent of the material being a solid not provided for in groups H01L2224/293 - H01L2224/29391, e.g. allotropes of carbon, fullerene, graphite, carbon-nanotubes, diamond	<administrative transfer to H10W 72/325 and H10W 72/353 simultaneously>

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D	H01L2224/29394	10	with a principal constituent of the material being a liquid not provided for in groups H01L2224/293 - H01L2224/29391	<administrative transfer to H10W 72/325 and H10W 72/353 simultaneously>
D	H01L2224/29395	10	with a principal constituent of the material being a gas not provided for in groups H01L2224/293 - H01L2224/29391	<administrative transfer to H10W 72/325 and H10W 72/353 simultaneously>
D	H01L2224/29398	10	with a principal constituent of the material being a combination of two or more materials in the form of a matrix with a filler, i.e. being a hybrid material, e.g. segmented structures, foams	<administrative transfer to H10W 72/325 and H10W 72/351 simultaneously>
D	H01L2224/29399	9	Coating material	<administrative transfer to H10W 72/325 and H10W 72/351 simultaneously>
D	H01L2224/294	10	with a principal constituent of the material being a metal or a metalloid, e.g. boron [B], silicon [Si], germanium [Ge], arsenic [As], antimony [Sb], tellurium [Te] and polonium [Po], and alloys thereof	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29401	11	the principal constituent melting at a temperature of less than 400°C	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29405	12	Gallium [Ga] as principal constituent	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29409	12	Indium [In] as principal constituent	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29411	12	Tin [Sn] as principal constituent	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29413	12	Bismuth [Bi] as principal constituent	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29414	12	Thallium [Tl] as principal constituent	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29416	12	Lead [Pb] as principal constituent	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>

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D	H01L2224/29417	11	the principal constituent melting at a temperature of greater than or equal to 400°C and less than 950°C	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29418	12	Zinc [Zn] as principal constituent	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/2942	12	Antimony [Sb] as principal constituent	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29423	12	Magnesium [Mg] as principal constituent	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29424	12	Aluminium [Al] as principal constituent	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29438	11	the principal constituent melting at a temperature of greater than or equal to 950°C and less than 1550°C	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29439	12	Silver [Ag] as principal constituent	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29444	12	Gold [Au] as principal constituent	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29447	12	Copper [Cu] as principal constituent	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29449	12	Manganese [Mn] as principal constituent	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29455	12	Nickel [Ni] as principal constituent	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29457	12	Cobalt [Co] as principal constituent	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/2946	12	Iron [Fe] as principal constituent	<administrative transfer to H10W 72/325 and

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				H10W 72/352 simultaneously>
D	H01L2224/29463	11	the principal constituent melting at a temperature of greater than 1550°C	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29464	12	Palladium [Pd] as principal constituent	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29466	12	Titanium [Ti] as principal constituent	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29469	12	Platinum [Pt] as principal constituent	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/2947	12	Zirconium [Zr] as principal constituent	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29471	12	Chromium [Cr] as principal constituent	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29472	12	Vanadium [V] as principal constituent	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29473	12	Rhodium [Rh] as principal constituent	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29476	12	Ruthenium [Ru] as principal constituent	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29478	12	Iridium [Ir] as principal constituent	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29479	12	Niobium [Nb] as principal constituent	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/2948	12	Molybdenum [Mo] as principal constituent	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>

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D	H01L2224/29481	12	Tantalum [Ta] as principal constituent	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29483	12	Rhenium [Re] as principal constituent	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29484	12	Tungsten [W] as principal constituent	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29486	10	with a principal constituent of the material being a non metallic, non metalloid inorganic material	<administrative transfer to H10W 72/325 and H10W 72/353 simultaneously>
D	H01L2224/29487	11	Ceramics, e.g. crystalline carbides, nitrides or oxides	<administrative transfer to H10W 72/325 and H10W 72/353 simultaneously>
D	H01L2224/29488	11	Glasses, e.g. amorphous oxides, nitrides or fluorides	<administrative transfer to H10W 72/325 and H10W 72/353 simultaneously>
D	H01L2224/2949	10	with a principal constituent of the material being a polymer, e.g. polyester, phenolic based polymer, epoxy	<administrative transfer to H10W 72/325 and H10W 72/354 simultaneously>
D	H01L2224/29491	11	The principal constituent being an elastomer, e.g. silicones, isoprene, neoprene	<administrative transfer to H10W 72/325 and H10W 72/354 simultaneously>
D	H01L2224/29493	10	with a principal constituent of the material being a solid not provided for in groups H01L2224/294 - H01L2224/29491, e.g. allotropes of carbon, fullerene, graphite, carbon-nanotubes, diamond	<administrative transfer to H10W 72/325 and H10W 72/353 simultaneously>
D	H01L2224/29494	10	with a principal constituent of the material being a liquid not provided for in groups H01L2224/294 - H01L2224/29491	<administrative transfer to H10W 72/325 and H10W 72/353 simultaneously>
D	H01L2224/29495	10	with a principal constituent of the material being a gas not provided for in groups H01L2224/294 - H01L2224/29491	<administrative transfer to H10W 72/325 and H10W 72/353 simultaneously>
D	H01L2224/29498	10	with a principal constituent of the material being a combination of two or more materials in the form of a matrix with a filler, i.e. being a hybrid material, e.g. segmented structures, foams	<administrative transfer to H10W 72/325 and H10W 72/351 simultaneously>

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D	H01L2224/29499	9	Shape or distribution of the fillers	<administrative transfer to H10W 72/325 and H10W 72/351 simultaneously>
D	H01L2224/2954	5	Coating	<administrative transfer to H10W 72/322>
D	H01L2224/29541	6	Structure	<administrative transfer to H10W 72/323>
D	H01L2224/2955	6	Shape	<administrative transfer to H10W 72/335>
D	H01L2224/29551	7	being non uniform	<administrative transfer to H10W 72/335>
D	H01L2224/29552	8	comprising protrusions or indentations	<administrative transfer to H10W 72/335>
D	H01L2224/29553	9	at the bonding interface of the layer connector, i.e. on the surface of the layer connector	<administrative transfer to H10W 72/335>
D	H01L2224/2956	6	Disposition	<administrative transfer to H10W 72/345>
D	H01L2224/29561	7	On the entire surface of the core, i.e. integral coating	<administrative transfer to H10W 72/345>
D	H01L2224/29562	7	On the entire exposed surface of the core	<administrative transfer to H10W 72/345>
D	H01L2224/29563	7	Only on parts of the surface of the core, i.e. partial coating	<administrative transfer to H10W 72/345>
D	H01L2224/29564	8	Only on the bonding interface of the layer connector	<administrative transfer to H10W 72/345>
D	H01L2224/29565	8	Only outside the bonding interface of the layer connector	<administrative transfer to H10W 72/345>
D	H01L2224/29566	8	Both on and outside the bonding interface of the layer connector	<administrative transfer to H10W 72/345>
D	H01L2224/2957	6	Single coating layer	<administrative transfer to H10W 72/322>
D	H01L2224/29575	6	Plural coating layers	<administrative transfer to H10W 72/323>
D	H01L2224/29576	7	being mutually engaged together, e.g. through inserts	<administrative transfer to H10W 72/323>
D	H01L2224/29578	7	being disposed next to each other, e.g. side-to-side arrangements	<administrative transfer to H10W 72/323>
D	H01L2224/2958	7	being stacked	<administrative transfer to H10W 72/323>
D	H01L2224/29582	8	Two-layer coating	<administrative transfer to H10W 72/323>
D	H01L2224/29583	8	Three-layer coating	<administrative transfer to H10W 72/323>
D	H01L2224/29584	8	Four-layer coating	<administrative transfer to H10W 72/323>

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D	H01L2224/29599	6	Material	<administrative transfer to H10W 72/355 and H10W 72/351 simultaneously>
D	H01L2224/296	7	with a principal constituent of the material being a metal or a metalloid, e.g. boron [B], silicon [Si], germanium [Ge], arsenic [As], antimony [Sb], tellurium [Te] and polonium [Po], and alloys thereof	<administrative transfer to H10W 72/355 and H10W 72/352 simultaneously>
D	H01L2224/29601	8	the principal constituent melting at a temperature of less than 400°C	<administrative transfer to H10W 72/355 and H10W 72/352 simultaneously>
D	H01L2224/29605	9	Gallium [Ga] as principal constituent	<administrative transfer to H10W 72/355 and H10W 72/352 simultaneously>
D	H01L2224/29609	9	Indium [In] as principal constituent	<administrative transfer to H10W 72/355 and H10W 72/352 simultaneously>
D	H01L2224/29611	9	Tin [Sn] as principal constituent	<administrative transfer to H10W 72/355 and H10W 72/352 simultaneously>
D	H01L2224/29613	9	Bismuth [Bi] as principal constituent	<administrative transfer to H10W 72/355 and H10W 72/352 simultaneously>
D	H01L2224/29614	9	Thallium [Tl] as principal constituent	<administrative transfer to H10W 72/355 and H10W 72/352 simultaneously>
D	H01L2224/29616	9	Lead [Pb] as principal constituent	<administrative transfer to H10W 72/355 and H10W 72/352 simultaneously>
D	H01L2224/29617	8	the principal constituent melting at a temperature of greater than or equal to 400°C and less than 950°C	<administrative transfer to H10W 72/355 and H10W 72/352 simultaneously>
D	H01L2224/29618	9	Zinc [Zn] as principal constituent	<administrative transfer to H10W 72/355 and H10W 72/352 simultaneously>
D	H01L2224/2962	9	Antimony [Sb] as principal constituent	<administrative transfer to H10W 72/355 and H10W 72/352 simultaneously>

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D	H01L2224/29623	9	Magnesium [Mg] as principal constituent	<administrative transfer to H10W 72/355 and H10W 72/352 simultaneously>
D	H01L2224/29624	9	Aluminium [Al] as principal constituent	<administrative transfer to H10W 72/355 and H10W 72/352 simultaneously>
D	H01L2224/29638	8	the principal constituent melting at a temperature of greater than or equal to 950°C and less than 1550°C	<administrative transfer to H10W 72/355 and H10W 72/352 simultaneously>
D	H01L2224/29639	9	Silver [Ag] as principal constituent	<administrative transfer to H10W 72/355 and H10W 72/352 simultaneously>
D	H01L2224/29644	9	Gold [Au] as principal constituent	<administrative transfer to H10W 72/355 and H10W 72/352 simultaneously>
D	H01L2224/29647	9	Copper [Cu] as principal constituent	<administrative transfer to H10W 72/355 and H10W 72/352 simultaneously>
D	H01L2224/29649	9	Manganese [Mn] as principal constituent	<administrative transfer to H10W 72/355 and H10W 72/352 simultaneously>
D	H01L2224/29655	9	Nickel [Ni] as principal constituent	<administrative transfer to H10W 72/355 and H10W 72/352 simultaneously>
D	H01L2224/29657	9	Cobalt [Co] as principal constituent	<administrative transfer to H10W 72/355 and H10W 72/352 simultaneously>
D	H01L2224/2966	9	Iron [Fe] as principal constituent	<administrative transfer to H10W 72/355 and H10W 72/352 simultaneously>
D	H01L2224/29663	8	the principal constituent melting at a temperature of greater than 1550°C	<administrative transfer to H10W 72/355 and H10W 72/352 simultaneously>
D	H01L2224/29664	9	Palladium [Pd] as principal constituent	<administrative transfer to H10W 72/355 and H10W 72/352 simultaneously>
D	H01L2224/29666	9	Titanium [Ti] as principal constituent	<administrative transfer to H10W 72/355 and

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				H10W 72/352 simultaneously>
D	H01L2224/29669	9	Platinum [Pt] as principal constituent	<administrative transfer to H10W 72/355 and H10W 72/352 simultaneously>
D	H01L2224/2967	9	Zirconium [Zr] as principal constituent	<administrative transfer to H10W 72/355 and H10W 72/352 simultaneously>
D	H01L2224/29671	9	Chromium [Cr] as principal constituent	<administrative transfer to H10W 72/355 and H10W 72/352 simultaneously>
D	H01L2224/29672	9	Vanadium [V] as principal constituent	<administrative transfer to H10W 72/355 and H10W 72/352 simultaneously>
D	H01L2224/29673	9	Rhodium [Rh] as principal constituent	<administrative transfer to H10W 72/355 and H10W 72/352 simultaneously>
D	H01L2224/29676	9	Ruthenium [Ru] as principal constituent	<administrative transfer to H10W 72/355 and H10W 72/352 simultaneously>
D	H01L2224/29678	9	Iridium [Ir] as principal constituent	<administrative transfer to H10W 72/355 and H10W 72/352 simultaneously>
D	H01L2224/29679	9	Niobium [Nb] as principal constituent	<administrative transfer to H10W 72/355 and H10W 72/352 simultaneously>
D	H01L2224/2968	9	Molybdenum [Mo] as principal constituent	<administrative transfer to H10W 72/355 and H10W 72/352 simultaneously>
D	H01L2224/29681	9	Tantalum [Ta] as principal constituent	<administrative transfer to H10W 72/355 and H10W 72/352 simultaneously>
D	H01L2224/29683	9	Rhenium [Re] as principal constituent	<administrative transfer to H10W 72/355 and H10W 72/352 simultaneously>
D	H01L2224/29684	9	Tungsten [W] as principal constituent	<administrative transfer to H10W 72/355 and H10W 72/352 simultaneously>

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D	H01L2224/29686	7	with a principal constituent of the material being a non metallic, non metalloid inorganic material	<administrative transfer to H10W 72/355 and H10W 72/353 simultaneously>
D	H01L2224/29687	8	Ceramics, e.g. crystalline carbides, nitrides or oxides	<administrative transfer to H10W 72/355 and H10W 72/353 simultaneously>
D	H01L2224/29688	8	Glasses, e.g. amorphous oxides, nitrides or fluorides	<administrative transfer to H10W 72/355 and H10W 72/353 simultaneously>
D	H01L2224/2969	7	with a principal constituent of the material being a polymer, e.g. polyester, phenolic based polymer, epoxy	<administrative transfer to H10W 72/355 and H10W 72/354 simultaneously>
D	H01L2224/29691	8	The principal constituent being an elastomer, e.g. silicones, isoprene, neoprene	<administrative transfer to H10W 72/355 and H10W 72/354 simultaneously>
D	H01L2224/29693	7	with a principal constituent of the material being a solid not provided for in groups H01L2224/296 - H01L2224/29691, e.g. allotropes of carbon, fullerene, graphite, carbon-nanotubes, diamond	<administrative transfer to H10W 72/355 and H10W 72/353 simultaneously>
D	H01L2224/29694	7	with a principal constituent of the material being a liquid not provided for in groups H01L2224/296 - H01L2224/29691	<administrative transfer to H10W 72/355 and H10W 72/353 simultaneously>
D	H01L2224/29695	7	with a principal constituent of the material being a gas not provided for in groups H01L2224/296 - H01L2224/29691	<administrative transfer to H10W 72/355 and H10W 72/353 simultaneously>
D	H01L2224/29698	7	with a principal constituent of the material being a combination of two or more materials in the form of a matrix with a filler, i.e. being a hybrid material, e.g. segmented structures, foams	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/351 simultaneously>
D	H01L2224/29699	8	Material of the matrix	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/351 simultaneously>
D	H01L2224/297	9	with a principal constituent of the material being a metal or a metalloid, e.g. boron [B], silicon [Si], germanium [Ge], arsenic [As], antimony [Sb], tellurium [Te] and polonium [Po], and alloys thereof	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29701	10	the principal constituent melting at a temperature of less than 400°C	<administrative transfer to H10W 72/355, H10W

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				72/325 and H10W 72/352 simultaneously>
D	H01L2224/29705	11	Gallium [Ga] as principal constituent	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29709	11	Indium [In] as principal constituent	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29711	11	Tin [Sn] as principal constituent	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29713	11	Bismuth [Bi] as principal constituent	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29714	11	Thallium [Tl] as principal constituent	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29716	11	Lead [Pb] as principal constituent	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29717	10	the principal constituent melting at a temperature of greater than or equal to 400°C and less than 950°C	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29718	11	Zinc [Zn] as principal constituent	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/2972	11	Antimony [Sb] as principal constituent	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29723	11	Magnesium [Mg] as principal constituent	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29724	11	Aluminium [Al] as principal constituent	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29738	10	the principal constituent melting at a temperature of greater than or equal to 950°C and less than 1550°C	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>

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D	H01L2224/29739	11	Silver [Ag] as principal constituent	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29744	11	Gold [Au] as principal constituent	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29747	11	Copper [Cu] as principal constituent	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29749	11	Manganese [Mn] as principal constituent	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29755	11	Nickel [Ni] as principal constituent	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29757	11	Cobalt [Co] as principal constituent	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/2976	11	Iron [Fe] as principal constituent	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29763	10	the principal constituent melting at a temperature of greater than 1550°C	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29764	11	Palladium [Pd] as principal constituent	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29766	11	Titanium [Ti] as principal constituent	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29769	11	Platinum [Pt] as principal constituent	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/2977	11	Zirconium [Zr] as principal constituent	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29771	11	Chromium [Cr] as principal constituent	<administrative transfer to H10W 72/355, H10W

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				72/325 and H10W 72/352 simultaneously>
D	H01L2224/29772	11	Vanadium [V] as principal constituent	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29773	11	Rhodium [Rh] as principal constituent	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29776	11	Ruthenium [Ru] as principal constituent	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29778	11	Iridium [Ir] as principal constituent	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29779	11	Niobium [Nb] as principal constituent	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/2978	11	Molybdenum [Mo] as principal constituent	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29781	11	Tantalum [Ta] as principal constituent	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29783	11	Rhenium [Re] as principal constituent	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29784	11	Tungsten [W] as principal constituent	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29786	9	with a principal constituent of the material being a non metallic, non metalloid inorganic material	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/353 simultaneously>
D	H01L2224/29787	10	Ceramics, e.g. crystalline carbides, nitrides or oxides	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/353 simultaneously>
D	H01L2224/29788	10	Glasses, e.g. amorphous oxides, nitrides or fluorides	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/353 simultaneously>

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D	H01L2224/2979	9	with a principal constituent of the material being a polymer, e.g. polyester, phenolic based polymer, epoxy	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/354 simultaneously>
D	H01L2224/29791	10	The principal constituent being an elastomer, e.g. silicones, isoprene, neoprene	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/354 simultaneously>
D	H01L2224/29793	9	with a principal constituent of the material being a solid not provided for in groups H01L2224/297 - H01L2224/29791, e.g. allotropes of carbon, fullerene, graphite, carbon-nanotubes, diamond	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/353 simultaneously>
D	H01L2224/29794	9	with a principal constituent of the material being a liquid not provided for in groups H01L2224/297 - H01L2224/29791	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/353 simultaneously>
D	H01L2224/29795	9	with a principal constituent of the material being a gas not provided for in groups H01L2224/297 - H01L2224/29791	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/353 simultaneously>
D	H01L2224/29798	8	Fillers	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/351 simultaneously>
D	H01L2224/29799	9	Base material	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/351 simultaneously>
D	H01L2224/298	10	with a principal constituent of the material being a metal or a metalloid, e.g. boron [B], silicon [Si], germanium [Ge], arsenic [As], antimony [Sb], tellurium [Te] and polonium [Po], and alloys thereof	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29801	11	the principal constituent melting at a temperature of less than 400°C	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29805	12	Gallium [Ga] as principal constituent	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29809	12	Indium [In] as principal constituent	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29811	12	Tin [Sn] as principal constituent	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>

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D	H01L2224/29813	12	Bismuth [Bi] as principal constituent	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29814	12	Thallium [Tl] as principal constituent	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29816	12	Lead [Pb] as principal constituent	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29817	11	the principal constituent melting at a temperature of greater than or equal to 400°C and less than 950°C	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29818	12	Zinc [Zn] as principal constituent	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/2982	12	Antimony [Sb] as principal constituent	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29823	12	Magnesium [Mg] as principal constituent	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29824	12	Aluminium [Al] as principal constituent	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29838	11	the principal constituent melting at a temperature of greater than or equal to 950°C and less than 1550°C	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29839	12	Silver [Ag] as principal constituent	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29844	12	Gold [Au] as principal constituent	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29847	12	Copper [Cu] as principal constituent	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29849	12	Manganese [Mn] as principal constituent	<administrative transfer to H10W 72/355, H10W

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				72/325 and H10W 72/352 simultaneously>
D	H01L2224/29855	12	Nickel [Ni] as principal constituent	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29857	12	Cobalt [Co] as principal constituent	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/2986	12	Iron [Fe] as principal constituent	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29863	11	the principal constituent melting at a temperature of greater than 1550°C	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29864	12	Palladium [Pd] as principal constituent	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29866	12	Titanium [Ti] as principal constituent	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29869	12	Platinum [Pt] as principal constituent	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/2987	12	Zirconium [Zr] as principal constituent	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29871	12	Chromium [Cr] as principal constituent	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29872	12	Vanadium [V] as principal constituent	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29873	12	Rhodium [Rh] as principal constituent	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29876	12	Ruthenium [Ru] as principal constituent	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>

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D	H01L2224/29878	12	Iridium [Ir] as principal constituent	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29879	12	Niobium [Nb] as principal constituent	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/2988	12	Molybdenum [Mo] as principal constituent	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29881	12	Tantalum [Ta] as principal constituent	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29883	12	Rhenium [Re] as principal constituent	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29884	12	Tungsten [W] as principal constituent	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29886	10	with a principal constituent of the material being a non metallic, non metalloid inorganic material	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/353 simultaneously>
D	H01L2224/29887	11	Ceramics, e.g. crystalline carbides, nitrides or oxides	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/353 simultaneously>
D	H01L2224/29888	11	Glasses, e.g. amorphous oxides, nitrides or fluorides	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/353 simultaneously>
D	H01L2224/2989	10	with a principal constituent of the material being a polymer, e.g. polyester, phenolic based polymer, epoxy	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/354 simultaneously>
D	H01L2224/29891	11	The principal constituent being an elastomer, e.g. silicones, isoprene, neoprene	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/354 simultaneously>
D	H01L2224/29893	10	with a principal constituent of the material being a solid not provided for in groups H01L2224/298 - H01L2224/29891, e.g. allotropes of carbon, fullerene, graphite, carbon-nanotubes, diamond	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/353 simultaneously>

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D	H01L2224/29894	10	with a principal constituent of the material being a liquid not provided for in groups H01L2224/298 - H01L2224/29891	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/353 simultaneously>
D	H01L2224/29895	10	with a principal constituent of the material being a gas not provided for in groups H01L2224/298 - H01L2224/29891	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/353 simultaneously>
D	H01L2224/29898	10	with a principal constituent of the material being a combination of two or more materials in the form of a matrix with a filler, i.e. being a hybrid material, e.g. segmented structures, foams	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/351 simultaneously>
D	H01L2224/29899	9	Coating material	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/351 simultaneously>
D	H01L2224/299	10	with a principal constituent of the material being a metal or a metalloid, e.g. boron [B], silicon [Si], germanium [Ge], arsenic [As], antimony [Sb], tellurium [Te] and polonium [Po], and alloys thereof	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29901	11	the principal constituent melting at a temperature of less than 400°C	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29905	12	Gallium [Ga] as principal constituent	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29909	12	Indium [In] as principal constituent	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29911	12	Tin [Sn] as principal constituent	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29913	12	Bismuth [Bi] as principal constituent	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29914	12	Thallium [Tl] as principal constituent	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29916	12	Lead [Pb] as principal constituent	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>

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D	H01L2224/29917	11	the principal constituent melting at a temperature of greater than or equal to 400°C and less than 950°C	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29918	12	Zinc [Zn] as principal constituent	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/2992	12	Antimony [Sb] as principal constituent	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29923	12	Magnesium [Mg] as principal constituent	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29924	12	Aluminium [Al] as principal constituent	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29938	11	the principal constituent melting at a temperature of greater than or equal to 950°C and less than 1550°C	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29939	12	Silver [Ag] as principal constituent	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29944	12	Gold [Au] as principal constituent	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29947	12	Copper [Cu] as principal constituent	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29949	12	Manganese [Mn] as principal constituent	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29955	12	Nickel [Ni] as principal constituent	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29957	12	Cobalt [Co] as principal constituent	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/2996	12	Iron [Fe] as principal constituent	<administrative transfer to H10W 72/355, H10W

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				72/325 and H10W 72/352 simultaneously>
D	H01L2224/29963	11	the principal constituent melting at a temperature of greater than 1550°C	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29964	12	Palladium [Pd] as principal constituent	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29966	12	Titanium [Ti] as principal constituent	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29969	12	Platinum [Pt] as principal constituent	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/2997	12	Zirconium [Zr] as principal constituent	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29971	12	Chromium [Cr] as principal constituent	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29972	12	Vanadium [V] as principal constituent	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29973	12	Rhodium [Rh] as principal constituent	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29976	12	Ruthenium [Ru] as principal constituent	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29978	12	Iridium [Ir] as principal constituent	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29979	12	Niobium [Nb] as principal constituent	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/2998	12	Molybdenum [Mo] as principal constituent	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>

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D	H01L2224/29981	12	Tantalum [Ta] as principal constituent	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29983	12	Rhenium [Re] as principal constituent	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29984	12	Tungsten [W] as principal constituent	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L2224/29986	10	with a principal constituent of the material being a non metallic, non metalloid inorganic material	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/353 simultaneously>
D	H01L2224/29987	11	Ceramics, e.g. crystalline carbides, nitrides or oxides	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/353 simultaneously>
D	H01L2224/29988	11	Glasses, e.g. amorphous oxides, nitrides or fluorides	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/353 simultaneously>
D	H01L2224/2999	10	with a principal constituent of the material being a polymer, e.g. polyester, phenolic based polymer, epoxy	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/354 simultaneously>
D	H01L2224/29991	11	The principal constituent being an elastomer, e.g. silicones, isoprene, neoprene	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/354 simultaneously>
D	H01L2224/29993	10	with a principal constituent of the material being a solid not provided for in groups H01L2224/299 - H01L2224/29991, e.g. allotropes of carbon, fullerene, graphite, carbon-nanotubes, diamond	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/353 simultaneously>
D	H01L2224/29994	10	with a principal constituent of the material being a liquid not provided for in groups H01L2224/299 - H01L2224/29991	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/353 simultaneously>
D	H01L2224/29995	10	with a principal constituent of the material being a gas not provided for in groups H01L2224/299 - H01L2224/29991	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/353 simultaneously>
D	H01L2224/29998	10	with a principal constituent of the material being a combination of two or more materials in the form of a matrix with a filler, i.e. being a hybrid material, e.g. segmented structures, foams	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/351 simultaneously>

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D	H01L2224/29999	9	Shape or distribution of the fillers	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/351 simultaneously>
D	H01L2224/30	4	of a plurality of layer connectors	<administrative transfer to H10W 72/30>
D	H01L2224/3001	5	Structure	<administrative transfer to H10W 72/328>
D	H01L2224/3003	6	Layer connectors having different sizes, e.g. different heights or widths	<administrative transfer to H10W 72/327>
D	H01L2224/3005	5	Shape	<administrative transfer to H10W 72/337>
D	H01L2224/30051	6	Layer connectors having different shapes	<administrative transfer to H10W 72/337>
D	H01L2224/301	5	Disposition	<administrative transfer to H10W 72/347>
D	H01L2224/30104	6	relative to the bonding areas, e.g. bond pads, of the semiconductor or solid-state body	<administrative transfer to H10W 72/347 and H10W 72/344 simultaneously>
D	H01L2224/3011	7	the layer connectors being bonded to at least one common bonding area	<administrative transfer to H10W 72/347 and H10W 72/344 simultaneously>
D	H01L2224/3012	6	Layout	<administrative transfer to H10W 72/348>
D	H01L2224/3013	7	Square or rectangular array	<administrative transfer to H10W 72/348>
D	H01L2224/30131	8	being uniform, i.e. having a uniform pitch across the array	<administrative transfer to H10W 72/348>
D	H01L2224/30132	8	being non uniform, i.e. having a non uniform pitch across the array	<administrative transfer to H10W 72/348>
D	H01L2224/30133	8	with a staggered arrangement, e.g. depopulated array	<administrative transfer to H10W 72/348>
D	H01L2224/30134	8	covering only portions of the surface to be connected	<administrative transfer to H10W 72/348>
D	H01L2224/30135	9	Covering only the peripheral area of the surface to be connected, i.e. peripheral arrangements	<administrative transfer to H10W 72/348>
D	H01L2224/30136	9	Covering only the central area of the surface to be connected, i.e. central arrangements	<administrative transfer to H10W 72/348>
D	H01L2224/3014	7	Circular array, i.e. array with radial symmetry	<administrative transfer to H10W 72/348>
D	H01L2224/30141	8	being uniform, i.e. having a uniform pitch across the array	<administrative transfer to H10W 72/348>
D	H01L2224/30142	8	being non uniform, i.e. having a non uniform pitch across the array	<administrative transfer to H10W 72/348>

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D	H01L2224/30143	8	covering only portions of the surface to be connected	<administrative transfer to H10W 72/348>
D	H01L2224/30145	9	Covering only the peripheral area of the surface to be connected, i.e. peripheral arrangements	<administrative transfer to H10W 72/348>
D	H01L2224/30146	9	Covering only the central area of the surface to be connected, i.e. central arrangements	<administrative transfer to H10W 72/348>
D	H01L2224/3015	7	Mirror array, i.e. array having only a reflection symmetry, i.e. bilateral symmetry	<administrative transfer to H10W 72/348>
D	H01L2224/30151	8	being uniform, i.e. having a uniform pitch across the array	<administrative transfer to H10W 72/348>
D	H01L2224/30152	8	being non uniform, i.e. having a non uniform pitch across the array	<administrative transfer to H10W 72/348>
D	H01L2224/30153	8	with a staggered arrangement, e.g. depopulated array	<administrative transfer to H10W 72/348>
D	H01L2224/30154	8	covering only portions of the surface to be connected	<administrative transfer to H10W 72/348>
D	H01L2224/30155	9	Covering only the peripheral area of the surface to be connected, i.e. peripheral arrangements	<administrative transfer to H10W 72/348>
D	H01L2224/30156	9	Covering only the central area of the surface to be connected, i.e. central arrangements	<administrative transfer to H10W 72/348>
D	H01L2224/3016	7	Random layout, i.e. layout with no symmetry	<administrative transfer to H10W 72/348>
D	H01L2224/30163	8	with a staggered arrangement	<administrative transfer to H10W 72/348>
D	H01L2224/30164	8	covering only portions of the surface to be connected	<administrative transfer to H10W 72/348>
D	H01L2224/30165	9	Covering only the peripheral area of the surface to be connected, i.e. peripheral arrangements	<administrative transfer to H10W 72/348>
D	H01L2224/30166	9	Covering only the central area of the surface to be connected, i.e. central arrangements	<administrative transfer to H10W 72/348>
D	H01L2224/30177	7	Combinations of arrays with different layouts	<administrative transfer to H10W 72/348>
D	H01L2224/30179	7	Corner adaptations, i.e. disposition of the layer connectors at the corners of the semiconductor or solid-state body	<administrative transfer to H10W 72/348>
D	H01L2224/3018	6	being disposed on at least two different sides of the body, e.g. dual array	<administrative transfer to H10W 72/347>
D	H01L2224/30181	7	On opposite sides of the body	<administrative transfer to H10W 72/347>
D	H01L2224/30183	7	On contiguous sides of the body	<administrative transfer to H10W 72/347>
D	H01L2224/305	5	Material	<administrative transfer to H10W 72/357>
D	H01L2224/30505	6	Layer connectors having different materials	<administrative transfer to H10W 72/357>

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D	H01L2224/3051	5	Function	<administrative transfer to H10W 72/367>
D	H01L2224/30515	6	Layer connectors having different functions	<administrative transfer to H10W 72/367>
D	H01L2224/30517	7	including layer connectors providing primarily mechanical bonding	<administrative transfer to H10W 72/367>
D	H01L2224/30519	7	including layer connectors providing primarily thermal dissipation	<administrative transfer to H10W 72/367 and H10W 72/365 simultaneously>
D	H01L2224/31	3	Structure, shape, material or disposition of the layer connectors after the connecting process	<administrative transfer to H10W 72/07351 and H10W 72/30 simultaneously>
D	H01L2224/32	4	of an individual layer connector	<administrative transfer to H10W 72/07351 and H10W 72/30 simultaneously>
D	H01L2224/3201	5	Structure	<administrative transfer to H10W 72/07352 and H10W 72/321 simultaneously>
D	H01L2224/32012	6	relative to the bonding area, e.g. bond pad	<administrative transfer to H10W 72/07352 and H10W 72/321 simultaneously>
D	H01L2224/32013	7	the layer connector being larger than the bonding area, e.g. bond pad	<administrative transfer to H10W 72/07352 and H10W 72/321 simultaneously>
D	H01L2224/32014	7	the layer connector being smaller than the bonding area, e.g. bond pad	<administrative transfer to H10W 72/07352 and H10W 72/321 simultaneously>
D	H01L2224/3205	5	Shape	<administrative transfer to H10W 72/07353 and H10W 72/331 simultaneously>
D	H01L2224/32052	6	in top view	<administrative transfer to H10W 72/07353 and H10W 72/332 simultaneously>
D	H01L2224/32053	7	being non uniform along the layer connector	<administrative transfer to H10W 72/07353 and H10W 72/332 simultaneously>
D	H01L2224/32054	7	being rectangular or square	<administrative transfer to H10W 72/07353 and H10W 72/332 simultaneously>

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D	H01L2224/32055	7	being circular or elliptic	<administrative transfer to H10W 72/07353 and H10W 72/332 simultaneously>
D	H01L2224/32056	7	comprising protrusions or indentations	<administrative transfer to H10W 72/07353 and H10W 72/332 simultaneously>
D	H01L2224/32057	6	in side view	<administrative transfer to H10W 72/07353 and H10W 72/334 simultaneously>
D	H01L2224/32058	7	being non uniform along the layer connector	<administrative transfer to H10W 72/07353 and H10W 72/334 simultaneously>
D	H01L2224/32059	7	comprising protrusions or indentations	<administrative transfer to H10W 72/07353 and H10W 72/334 simultaneously>
D	H01L2224/3207	6	of bonding interfaces, e.g. interlocking features	<administrative transfer to H10W 72/07353 and H10W 72/331 simultaneously>
D	H01L2224/321	5	Disposition	<administrative transfer to H10W 72/07354 and H10W 72/341 simultaneously>
D	H01L2224/32104	6	relative to the bonding area, e.g. bond pad	<administrative transfer to H10W 72/07354 and H10W 72/344 simultaneously>
D	H01L2224/32105	7	the layer connector connecting bonding areas being not aligned with respect to each other	<administrative transfer to H10W 72/07354 and H10W 72/344 simultaneously>
D	H01L2224/32106	7	the layer connector connecting one bonding area to at least two respective bonding areas	<administrative transfer to H10W 72/07354 and H10W 72/344 simultaneously>
D	H01L2224/32111	6	the layer connector being disposed in a recess of the surface	<administrative transfer to H10W 72/07354 and H10W 72/342 simultaneously>
D	H01L2224/32112	6	the layer connector being at least partially embedded in the surface	<administrative transfer to H10W 72/07354 and H10W 72/342 simultaneously>
D	H01L2224/32113	6	the whole layer connector protruding from the surface	<administrative transfer to H10W 72/07354 and

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				H10W 72/342 simultaneously>
D	H01L2224/3213	6	the layer connector connecting within a semiconductor or solid-state body, i.e. connecting two bonding areas on the same semiconductor or solid-state body	<administrative transfer to H10W 72/07354 and H10W 72/341 simultaneously>
D	H01L2224/32135	6	the layer connector connecting between different semiconductor or solid-state bodies, i.e. chip-to-chip	<administrative transfer to H10W 90/731>
D	H01L2224/32137	7	the bodies being arranged next to each other, e.g. on a common substrate	<administrative transfer to H10W 90/733>
D	H01L2224/32141	7	the bodies being arranged on opposite sides of a substrate, e.g. mirror arrangements	<administrative transfer to H10W 90/731>
D	H01L2224/32145	7	the bodies being stacked	<administrative transfer to H10W 90/732>
D	H01L2224/32146	8	the layer connector connecting to a via connection in the semiconductor or solid-state body	<administrative transfer to H10W 90/732>
D	H01L2224/32147	8	the layer connector connecting to a bonding area disposed in a recess of the surface	<administrative transfer to H10W 90/732>
D	H01L2224/32148	8	the layer connector connecting to a bonding area protruding from the surface	<administrative transfer to H10W 90/732>
D	H01L2224/32151	6	the layer connector connecting between a semiconductor or solid-state body and an item not being a semiconductor or solid-state body, e.g. chip-to-substrate, chip-to-passive	<administrative transfer to H10W 90/731>
D	H01L2224/32153	7	the body and the item being arranged next to each other, e.g. on a common substrate	<administrative transfer to H10W 90/731>
D	H01L2224/32155	8	the item being non-metallic, e.g. being an insulating substrate with or without metallisation	<administrative transfer to H10W 90/735>
D	H01L2224/32157	9	the layer connector connecting to a bond pad of the item	<administrative transfer to H10W 90/735>
D	H01L2224/3216	9	the layer connector connecting to a pin of the item	<administrative transfer to H10W 90/735>
D	H01L2224/32163	9	the layer connector connecting to a potential ring of the item	<administrative transfer to H10W 90/735>
D	H01L2224/32165	9	the layer connector connecting to a via metallisation of the item	<administrative transfer to H10W 90/735>
D	H01L2224/32167	9	the layer connector connecting to a bonding area disposed in a recess of the surface of the item	<administrative transfer to H10W 90/735>
D	H01L2224/32168	9	the layer connector connecting to a bonding area protruding from the surface of the item	<administrative transfer to H10W 90/735>
D	H01L2224/32175	8	the item being metallic	<administrative transfer to H10W 90/737>
D	H01L2224/32183	9	the layer connector connecting to a potential ring of the item	<administrative transfer to H10W 90/737>

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D	H01L2224/32187	9	the layer connector connecting to a bonding area disposed in a recess of the surface of the item	<administrative transfer to H10W 90/737>
D	H01L2224/32188	9	the layer connector connecting to a bonding area protruding from the surface of the item	<administrative transfer to H10W 90/737>
D	H01L2224/32195	8	the item being a discrete passive component	<administrative transfer to H10W 90/739>
D	H01L2224/32197	9	the layer connector connecting to a bonding area disposed in a recess of the surface of the item	<administrative transfer to H10W 90/739>
D	H01L2224/32198	9	the layer connector connecting to a bonding area protruding from the surface of the item	<administrative transfer to H10W 90/739>
D	H01L2224/32221	7	the body and the item being stacked	<administrative transfer to H10W 90/731>
D	H01L2224/32225	8	the item being non-metallic, e.g. insulating substrate with or without metallisation	<administrative transfer to H10W 90/734>
D	H01L2224/32227	9	the layer connector connecting to a bond pad of the item	<administrative transfer to H10W 90/734>
D	H01L2224/3223	9	the layer connector connecting to a pin of the item	<administrative transfer to H10W 90/734>
D	H01L2224/32233	9	the layer connector connecting to a potential ring of the item	<administrative transfer to H10W 90/734>
D	H01L2224/32235	9	the layer connector connecting to a via metallisation of the item	<administrative transfer to H10W 90/734>
D	H01L2224/32237	9	the layer connector connecting to a bonding area disposed in a recess of the surface of the item	<administrative transfer to H10W 90/734>
D	H01L2224/32238	9	the layer connector connecting to a bonding area protruding from the surface of the item	<administrative transfer to H10W 90/734>
D	H01L2224/3224	9	the layer connector connecting between the body and an opposite side of the item with respect to the body	<administrative transfer to H10W 90/734>
D	H01L2224/32245	8	the item being metallic	<administrative transfer to H10W 90/736>
D	H01L2224/32253	9	the layer connector connecting to a potential ring of the item	<administrative transfer to H10W 90/736>
D	H01L2224/32257	9	the layer connector connecting to a bonding area disposed in a recess of the surface of the item	<administrative transfer to H10W 90/736>
D	H01L2224/32258	9	the layer connector connecting to a bonding area protruding from the surface of the item	<administrative transfer to H10W 90/736>
D	H01L2224/3226	9	the layer connector connecting between the body and an opposite side of the item with respect to the body	<administrative transfer to H10W 90/736>
D	H01L2224/32265	8	the item being a discrete passive component	<administrative transfer to H10W 90/738>

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D	H01L2224/32267	9	the layer connector connecting to a bonding area disposed in a recess of the surface of the item	<administrative transfer to H10W 90/738>
D	H01L2224/32268	9	the layer connector connecting to a bonding area protruding from the surface of the item	<administrative transfer to H10W 90/738>
D	H01L2224/325	5	Material	<administrative transfer to H10W 72/07355 and H10W 72/351 simultaneously>
D	H01L2224/32501	6	at the bonding interface	<administrative transfer to H10W 72/07355 and H10W 72/351 simultaneously>
D	H01L2224/32502	7	comprising an eutectic alloy	<administrative transfer to H10W 72/07355 and H10W 72/3524 simultaneously>
D	H01L2224/32503	7	comprising an intermetallic compound	<administrative transfer to H10W 72/07355 and H10W 72/3528 simultaneously>
D	H01L2224/32505	6	outside the bonding interface, e.g. in the bulk of the layer connector	<administrative transfer to H10W 72/07355 and H10W 72/351 simultaneously>
D	H01L2224/32506	7	comprising an eutectic alloy	<administrative transfer to H10W 72/07355 and H10W 72/3524 simultaneously>
D	H01L2224/32507	7	comprising an intermetallic compound	<administrative transfer to H10W 72/07355 and H10W 72/3528 simultaneously>
D	H01L2224/33	4	of a plurality of layer connectors	<administrative transfer to H10W 72/07351 and H10W 72/30 simultaneously>
D	H01L2224/3301	5	Structure	<administrative transfer to H10W 72/07352 and H10W 72/328 simultaneously>
D	H01L2224/3303	6	Layer connectors having different sizes, e.g. different heights or widths	<administrative transfer to H10W 72/07352 and H10W 72/327 simultaneously>
D	H01L2224/3305	5	Shape	<administrative transfer to H10W 72/07353 and H10W 72/337 simultaneously>

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D	H01L2224/33051	6	Layer connectors having different shapes	<administrative transfer to H10W 72/07353 and H10W 72/337 simultaneously>
D	H01L2224/33055	7	of their bonding interfaces	<administrative transfer to H10W 72/07353 and H10W 72/337 simultaneously>
D	H01L2224/331	5	Disposition	<administrative transfer to H10W 72/07354 and H10W 72/347 simultaneously>
D	H01L2224/33104	6	relative to the bonding areas, e.g. bond pads	<administrative transfer to H10W 72/07354, H10W 72/344 and H10W 72/347 simultaneously>
D	H01L2224/33106	7	the layer connectors being bonded to at least one common bonding area	<administrative transfer to H10W 72/07354, H10W 72/344 and H10W 72/347 simultaneously>
D	H01L2224/33107	8	the layer connectors connecting two common bonding areas	<administrative transfer to H10W 72/07354, H10W 72/344 and H10W 72/347 simultaneously>
D	H01L2224/3312	6	Layout	<administrative transfer to H10W 72/07354 and H10W 72/348 simultaneously>
D	H01L2224/3313	7	Square or rectangular array	<administrative transfer to H10W 72/07354 and H10W 72/348 simultaneously>
D	H01L2224/33132	8	being non uniform, i.e. having a non uniform pitch across the array	<administrative transfer to H10W 72/07354 and H10W 72/348 simultaneously>
D	H01L2224/33133	8	with a staggered arrangement, e.g. depopulated array	<administrative transfer to H10W 72/07354 and H10W 72/348 simultaneously>
D	H01L2224/33134	8	covering only portions of the surface to be connected	<administrative transfer to H10W 72/07354 and H10W 72/348 simultaneously>
D	H01L2224/33135	9	Covering only the peripheral area of the surface to be connected, i.e. peripheral arrangements	<administrative transfer to H10W 72/07354 and H10W 72/348 simultaneously>
D	H01L2224/3314	7	Circular array, i.e. array with radial symmetry	<administrative transfer to H10W 72/07354 and

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				H10W 72/348 simultaneously>
D	H01L2224/33142	8	being non uniform, i.e. having a non uniform pitch across the array	<administrative transfer to H10W 72/07354 and H10W 72/348 simultaneously>
D	H01L2224/33143	8	with a staggered arrangement	<administrative transfer to H10W 72/07354 and H10W 72/348 simultaneously>
D	H01L2224/33144	8	covering only portions of the surface to be connected	<administrative transfer to H10W 72/07354 and H10W 72/348 simultaneously>
D	H01L2224/33145	9	Covering only the peripheral area of the surface to be connected, i.e. peripheral arrangements	<administrative transfer to H10W 72/07354 and H10W 72/348 simultaneously>
D	H01L2224/3315	7	Mirror array, i.e. array having only a reflection symmetry, i.e. bilateral symmetry	<administrative transfer to H10W 72/07354 and H10W 72/348 simultaneously>
D	H01L2224/33151	8	being uniform, i.e. having a uniform pitch across the array	<administrative transfer to H10W 72/07354 and H10W 72/348 simultaneously>
D	H01L2224/33152	8	being non uniform, i.e. having a non uniform pitch across the array	<administrative transfer to H10W 72/07354 and H10W 72/348 simultaneously>
D	H01L2224/33153	8	with a staggered arrangement, e.g. depopulated array	<administrative transfer to H10W 72/07354 and H10W 72/348 simultaneously>
D	H01L2224/33154	8	covering only portions of the surface to be connected	<administrative transfer to H10W 72/07354 and H10W 72/348 simultaneously>
D	H01L2224/33155	9	Covering only the peripheral area of the surface to be connected, i.e. peripheral arrangements	<administrative transfer to H10W 72/07354 and H10W 72/348 simultaneously>
D	H01L2224/33156	9	Covering only the central area of the surface to be connected, i.e. central arrangements	<administrative transfer to H10W 72/07354 and H10W 72/348 simultaneously>
D	H01L2224/3316	7	Random layout, i.e. layout with no symmetry	<administrative transfer to H10W 72/07354 and H10W 72/348 simultaneously>

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D	H01L2224/33163	8	with a staggered arrangement	<administrative transfer to H10W 72/07354 and H10W 72/348 simultaneously>
D	H01L2224/33164	8	covering only portions of the surface to be connected	<administrative transfer to H10W 72/07354 and H10W 72/348 simultaneously>
D	H01L2224/33165	9	Covering only the peripheral area of the surface to be connected, i.e. peripheral arrangements	<administrative transfer to H10W 72/07354 and H10W 72/348 simultaneously>
D	H01L2224/33177	7	Combinations of arrays with different layouts	<administrative transfer to H10W 72/07354 and H10W 72/348 simultaneously>
D	H01L2224/33179	7	Corner adaptations, i.e. disposition of the layer connectors at the corners of the semiconductor or solid-state body	<administrative transfer to H10W 72/07354 and H10W 72/348 simultaneously>
D	H01L2224/3318	6	being disposed on at least two different sides of the body, e.g. dual array	<administrative transfer to H10W 72/07354 and H10W 72/347 simultaneously>
D	H01L2224/33181	7	On opposite sides of the body	<administrative transfer to H10W 72/07354 and H10W 72/347 simultaneously>
D	H01L2224/33183	7	On contiguous sides of the body	<administrative transfer to H10W 72/07354 and H10W 72/347 simultaneously>
D	H01L2224/335	5	Material	<administrative transfer to H10W 72/07355 and H10W 72/357 simultaneously>
D	H01L2224/33505	6	Layer connectors having different materials	<administrative transfer to H10W 72/07355 and H10W 72/357 simultaneously>
D	H01L2224/3351	5	Function	<administrative transfer to H10W 72/07351 and H10W 72/367 simultaneously>
D	H01L2224/33515	6	Layer connectors having different functions	<administrative transfer to H10W 72/07351 and H10W 72/367 simultaneously>
D	H01L2224/33517	7	including layer connectors providing primarily mechanical support	<administrative transfer to H10W 72/07351 and

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				H10W 72/367 simultaneously>
D	H01L2224/33519	7	including layer connectors providing primarily thermal dissipation	<administrative transfer to H10W 72/07351, H10W 72/365 and H10W 72/367 simultaneously>
D	H01L2224/34	2	Strap connectors, e.g. copper straps for grounding power devices; Manufacturing methods related thereto	<administrative transfer to H10W 72/016>
D	H01L2224/35	3	Manufacturing methods	<administrative transfer to H10W 72/016>
D	H01L2224/35001	4	Involving a temporary auxiliary member not forming part of the manufacturing apparatus, e.g. removable or sacrificial coating, film or substrate	<administrative transfer to H10W 72/01604>
D	H01L2224/351	4	Pre-treatment of the preform connector	<administrative transfer to H10W 72/016>
D	H01L2224/3512	5	Applying permanent coating, e.g. in-situ coating	<administrative transfer to H10W 72/01615>
D	H01L2224/35125	6	Plating, e.g. electroplating, electroless plating	<administrative transfer to H10W 72/016>
D	H01L2224/352	4	Mechanical processes	<administrative transfer to H10W 72/016>
D	H01L2224/3521	5	Pulling	<administrative transfer to H10W 72/016>
D	H01L2224/355	4	Modification of a pre-existing material	<administrative transfer to H10W 72/016>
D	H01L2224/3551	5	Sintering	<administrative transfer to H10W 72/016>
D	H01L2224/3552	5	Anodisation	<administrative transfer to H10W 72/016>
D	H01L2224/357	4	Involving monitoring, e.g. feedback loop	<administrative transfer to H10W 72/016>
D	H01L2224/358	4	Post-treatment of the connector	<administrative transfer to H10W 72/016>
D	H01L2224/3581	5	Cleaning, e.g. oxide removal step, desmearing	<administrative transfer to H10W 72/01671>
D	H01L2224/3582	5	Applying permanent coating, e.g. in-situ coating	<administrative transfer to H10W 72/01615>
D	H01L2224/35821	6	Spray coating	<administrative transfer to H10W 72/01615>
D	H01L2224/35822	6	Dip coating	<administrative transfer to H10W 72/01615>
D	H01L2224/35823	6	Immersion coating, e.g. solder bath	<administrative transfer to H10W 72/01615>
D	H01L2224/35824	6	Chemical solution deposition [CSD], i.e. using a liquid precursor	<administrative transfer to H10W 72/01615>

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D	H01L2224/35825	6	Plating, e.g. electroplating, electroless plating	<administrative transfer to H10W 72/01615>
D	H01L2224/35826	6	Physical vapour deposition [PVD], e.g. evaporation, sputtering	<administrative transfer to H10W 72/01615>
D	H01L2224/35827	6	Chemical vapour deposition [CVD], e.g. laser CVD	<administrative transfer to H10W 72/01615>
D	H01L2224/3583	5	Reworking	<administrative transfer to H10W 72/01651>
D	H01L2224/35831	6	with a chemical process, e.g. with etching of the connector	<administrative transfer to H10W 72/01661 and H10W 72/01653 simultaneously>
D	H01L2224/35847	6	with a mechanical process, e.g. with flattening of the connector	<administrative transfer to H10W 72/01661>
D	H01L2224/35848	5	Thermal treatments, e.g. annealing, controlled cooling	<administrative transfer to H10W 72/016>
D	H01L2224/35985	4	Methods of manufacturing strap connectors involving a specific sequence of method steps	<administrative transfer to H10W 72/016>
D	H01L2224/35986	5	with repetition of the same manufacturing step	<administrative transfer to H10W 72/016>
D	H01L2224/36	3	Structure, shape, material or disposition of the strap connectors prior to the connecting process	<administrative transfer to H10W 72/60>
D	H01L2224/37	4	of an individual strap connector	<administrative transfer to H10W 72/60>
D	H01L2224/37001	5	Core members of the connector	<administrative transfer to H10W 72/60>
D	H01L2224/37005	6	Structure	<administrative transfer to H10W 72/621>
D	H01L2224/3701	6	Shape	<administrative transfer to H10W 72/631>
D	H01L2224/37011	7	comprising apertures or cavities	<administrative transfer to H10W 72/631>
D	H01L2224/37012	7	Cross-sectional shape	<administrative transfer to H10W 72/634>
D	H01L2224/37013	8	being non uniform along the connector	<administrative transfer to H10W 72/634>
D	H01L2224/3702	6	Disposition	<administrative transfer to H10W 72/641>
D	H01L2224/37025	6	Plural core members	<administrative transfer to H10W 72/624>
D	H01L2224/37026	7	being mutually engaged together, e.g. through inserts	<administrative transfer to H10W 72/624>
D	H01L2224/37028	7	Side-to-side arrangements	<administrative transfer to H10W 72/624>
D	H01L2224/3703	7	Stacked arrangements	<administrative transfer to H10W 72/623>

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D	H01L2224/37032	8	Two-layer arrangements	<administrative transfer to H10W 72/623>
D	H01L2224/37033	8	Three-layer arrangements	<administrative transfer to H10W 72/623>
D	H01L2224/37034	8	Four-layer arrangements	<administrative transfer to H10W 72/623>
D	H01L2224/37099	6	Material	<administrative transfer to H10W 72/651>
D	H01L2224/371	7	with a principal constituent of the material being a metal or a metalloid, e.g. boron [B], silicon [Si], germanium [Ge], arsenic [As], antimony [Sb], tellurium [Te] and polonium [Po], and alloys thereof	<administrative transfer to H10W 72/652>
D	H01L2224/37101	8	the principal constituent melting at a temperature of less than 400°C	<administrative transfer to H10W 72/652>
D	H01L2224/37105	9	Gallium [Ga] as principal constituent	<administrative transfer to H10W 72/652>
D	H01L2224/37109	9	Indium [In] as principal constituent	<administrative transfer to H10W 72/652>
D	H01L2224/37111	9	Tin [Sn] as principal constituent	<administrative transfer to H10W 72/652>
D	H01L2224/37113	9	Bismuth [Bi] as principal constituent	<administrative transfer to H10W 72/652>
D	H01L2224/37114	9	Thallium [Tl] as principal constituent	<administrative transfer to H10W 72/652>
D	H01L2224/37116	9	Lead [Pb] as principal constituent	<administrative transfer to H10W 72/652>
D	H01L2224/37117	8	the principal constituent melting at a temperature of greater than or equal to 400°C and less than 950°C	<administrative transfer to H10W 72/652>
D	H01L2224/37118	9	Zinc [Zn] as principal constituent	<administrative transfer to H10W 72/652>
D	H01L2224/3712	9	Antimony [Sb] as principal constituent	<administrative transfer to H10W 72/652>
D	H01L2224/37123	9	Magnesium [Mg] as principal constituent	<administrative transfer to H10W 72/652>
D	H01L2224/37124	9	Aluminium [Al] as principal constituent	<administrative transfer to H10W 72/652>
D	H01L2224/37138	8	the principal constituent melting at a temperature of greater than or equal to 950°C and less than 1550°C	<administrative transfer to H10W 72/652>
D	H01L2224/37139	9	Silver [Ag] as principal constituent	<administrative transfer to H10W 72/652>
D	H01L2224/37144	9	Gold [Au] as principal constituent	<administrative transfer to H10W 72/652>
D	H01L2224/37147	9	Copper [Cu] as principal constituent	<administrative transfer to H10W 72/652>

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D	H01L2224/37149	9	Manganese [Mn] as principal constituent	<administrative transfer to H10W 72/652>
D	H01L2224/37155	9	Nickel [Ni] as principal constituent	<administrative transfer to H10W 72/652>
D	H01L2224/37157	9	Cobalt [Co] as principal constituent	<administrative transfer to H10W 72/652>
D	H01L2224/3716	9	Iron [Fe] as principal constituent	<administrative transfer to H10W 72/652>
D	H01L2224/37163	8	the principal constituent melting at a temperature of greater than 1550°C	<administrative transfer to H10W 72/652>
D	H01L2224/37164	9	Palladium [Pd] as principal constituent	<administrative transfer to H10W 72/652>
D	H01L2224/37166	9	Titanium [Ti] as principal constituent	<administrative transfer to H10W 72/652>
D	H01L2224/37169	9	Platinum [Pt] as principal constituent	<administrative transfer to H10W 72/652>
D	H01L2224/3717	9	Zirconium [Zr] as principal constituent	<administrative transfer to H10W 72/652>
D	H01L2224/37171	9	Chromium [Cr] as principal constituent	<administrative transfer to H10W 72/652>
D	H01L2224/37172	9	Vanadium [V] as principal constituent	<administrative transfer to H10W 72/652>
D	H01L2224/37173	9	Rhodium [Rh] as principal constituent	<administrative transfer to H10W 72/652>
D	H01L2224/37176	9	Ruthenium [Ru] as principal constituent	<administrative transfer to H10W 72/652>
D	H01L2224/37178	9	Iridium [Ir] as principal constituent	<administrative transfer to H10W 72/652>
D	H01L2224/37179	9	Niobium [Nb] as principal constituent	<administrative transfer to H10W 72/652>
D	H01L2224/3718	9	Molybdenum [Mo] as principal constituent	<administrative transfer to H10W 72/652>
D	H01L2224/37181	9	Tantalum [Ta] as principal constituent	<administrative transfer to H10W 72/652>
D	H01L2224/37183	9	Rhenium [Re] as principal constituent	<administrative transfer to H10W 72/652>
D	H01L2224/37184	9	Tungsten [W] as principal constituent	<administrative transfer to H10W 72/652>
D	H01L2224/37186	7	with a principal constituent of the material being a non metallic, non metalloid inorganic material	<administrative transfer to H10W 72/653>
D	H01L2224/37187	8	Ceramics, e.g. crystalline carbides, nitrides or oxides	<administrative transfer to H10W 72/653>
D	H01L2224/37188	8	Glasses, e.g. amorphous oxides, nitrides or fluorides	<administrative transfer to H10W 72/653>
D	H01L2224/3719	7	with a principal constituent of the material being a polymer, e.g. polyester, phenolic based polymer, epoxy	<administrative transfer to H10W 72/653>

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D	H01L2224/37191	8	The principal constituent being an elastomer, e.g. silicones, isoprene, neoprene	<administrative transfer to H10W 72/653>
D	H01L2224/37193	7	with a principal constituent of the material being a solid not provided for in groups H01L2224/371 - H01L2224/37191, e.g. allotropes of carbon, fullerene, graphite, carbon-nanotubes, diamond	<administrative transfer to H10W 72/653>
D	H01L2224/37194	7	with a principal constituent of the material being a liquid not provided for in groups H01L2224/371 - H01L2224/37191	<administrative transfer to H10W 72/653>
D	H01L2224/37195	7	with a principal constituent of the material being a gas not provided for in groups H01L2224/371 - H01L2224/37191	<administrative transfer to H10W 72/653>
D	H01L2224/37198	7	with a principal constituent of the material being a combination of two or more materials in the form of a matrix with a filler, i.e. being a hybrid material, e.g. segmented structures, foams	<administrative transfer to H10W 72/625>
D	H01L2224/37199	8	Material of the matrix	<administrative transfer to H10W 72/625>
D	H01L2224/372	9	with a principal constituent of the material being a metal or a metalloid, e.g. boron [B], silicon [Si], germanium [Ge], arsenic [As], antimony [Sb], tellurium [Te] and polonium [Po], and alloys thereof	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37201	10	the principal constituent melting at a temperature of less than 400°C	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37205	11	Gallium [Ga] as principal constituent	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37209	11	Indium [In] as principal constituent	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37211	11	Tin [Sn] as principal constituent	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37213	11	Bismuth [Bi] as principal constituent	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37214	11	Thallium [Tl] as principal constituent	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>

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D	H01L2224/37216	11	Lead [Pb] as principal constituent	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37217	10	the principal constituent melting at a temperature of greater than or equal to 400°C and less than 950°C	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37218	11	Zinc [Zn] as principal constituent	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/3722	11	Antimony [Sb] as principal constituent	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37223	11	Magnesium [Mg] as principal constituent	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37224	11	Aluminium [Al] as principal constituent	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37238	10	the principal constituent melting at a temperature of greater than or equal to 950°C and less than 1550°C	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37239	11	Silver [Ag] as principal constituent	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37244	11	Gold [Au] as principal constituent	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37247	11	Copper [Cu] as principal constituent	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37249	11	Manganese [Mn] as principal constituent	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37255	11	Nickel [Ni] as principal constituent	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37257	11	Cobalt [Co] as principal constituent	<administrative transfer to H10W 72/625 and

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				H10W 72/652 simultaneously>
D	H01L2224/3726	11	Iron [Fe] as principal constituent	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37263	10	the principal constituent melting at a temperature of greater than 1550°C	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37264	11	Palladium [Pd] as principal constituent	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37266	11	Titanium [Ti] as principal constituent	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37269	11	Platinum [Pt] as principal constituent	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/3727	11	Zirconium [Zr] as principal constituent	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37271	11	Chromium [Cr] as principal constituent	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37272	11	Vanadium [V] as principal constituent	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37273	11	Rhodium [Rh] as principal constituent	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37276	11	Ruthenium [Ru] as principal constituent	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37278	11	Iridium [Ir] as principal constituent	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37279	11	Niobium [Nb] as principal constituent	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>

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D	H01L2224/3728	11	Molybdenum [Mo] as principal constituent	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37281	11	Tantalum [Ta] as principal constituent	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37283	11	Rhenium [Re] as principal constituent	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37284	11	Tungsten [W] as principal constituent	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37286	9	with a principal constituent of the material being a non metallic, non metalloid inorganic material	<administrative transfer to H10W 72/625 and H10W 72/653 simultaneously>
D	H01L2224/37287	10	Ceramics, e.g. crystalline carbides, nitrides or oxides	<administrative transfer to H10W 72/625 and H10W 72/653 simultaneously>
D	H01L2224/37288	10	Glasses, e.g. amorphous oxides, nitrides or fluorides	<administrative transfer to H10W 72/625 and H10W 72/653 simultaneously>
D	H01L2224/3729	9	with a principal constituent of the material being a polymer, e.g. polyester, phenolic based polymer, epoxy	<administrative transfer to H10W 72/625 and H10W 72/653 simultaneously>
D	H01L2224/37291	10	The principal constituent being an elastomer, e.g. silicones, isoprene, neoprene	<administrative transfer to H10W 72/625 and H10W 72/653 simultaneously>
D	H01L2224/37293	9	with a principal constituent of the material being a solid not provided for in groups H01L2224/372 - H01L2224/37291, e.g. allotropes of carbon, fullerene, graphite, carbon-nanotubes, diamond	<administrative transfer to H10W 72/625 and H10W 72/653 simultaneously>
D	H01L2224/37294	9	with a principal constituent of the material being a liquid not provided for in groups H01L2224/372 - H01L2224/37291	<administrative transfer to H10W 72/625 and H10W 72/653 simultaneously>
D	H01L2224/37295	9	with a principal constituent of the material being a gas not provided for in groups H01L2224/372 - H01L2224/37291	<administrative transfer to H10W 72/625 and H10W 72/653 simultaneously>

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D	H01L2224/37298	8	Fillers	<administrative transfer to H10W 72/625 and H10W 72/651 simultaneously>
D	H01L2224/37299	9	Base material	<administrative transfer to H10W 72/625 and H10W 72/651 simultaneously>
D	H01L2224/373	10	with a principal constituent of the material being a metal or a metalloid, e.g. boron [B], silicon [Si], germanium [Ge], arsenic [As], antimony [Sb], tellurium [Te] and polonium [Po], and alloys thereof	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37301	11	the principal constituent melting at a temperature of less than 400°C	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37305	12	Gallium [Ga] as principal constituent	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37309	12	Indium [In] as principal constituent	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37311	12	Tin [Sn] as principal constituent	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37313	12	Bismuth [Bi] as principal constituent	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37314	12	Thallium [Tl] as principal constituent	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37316	12	Lead [Pb] as principal constituent	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37317	11	the principal constituent melting at a temperature of greater than or equal to 400°C and less than 950°C	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37318	12	Zinc [Zn] as principal constituent	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>

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D	H01L2224/3732	12	Antimony [Sb] as principal constituent	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37323	12	Magnesium [Mg] as principal constituent	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37324	12	Aluminium [Al] as principal constituent	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37338	11	the principal constituent melting at a temperature of greater than or equal to 950°C and less than 1550°C	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37339	12	Silver [Ag] as principal constituent	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37344	12	Gold [Au] as principal constituent	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37347	12	Copper [Cu] as principal constituent	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37349	12	Manganese [Mn] as principal constituent	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37355	12	Nickel [Ni] as principal constituent	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37357	12	Cobalt [Co] as principal constituent	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/3736	12	Iron [Fe] as principal constituent	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37363	11	the principal constituent melting at a temperature of greater than 1550°C	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37364	12	Palladium [Pd] as principal constituent	<administrative transfer to H10W 72/625 and

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				H10W 72/652 simultaneously>
D	H01L2224/37366	12	Titanium [Ti] as principal constituent	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37369	12	Platinum [Pt] as principal constituent	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/3737	12	Zirconium [Zr] as principal constituent	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37371	12	Chromium [Cr] as principal constituent	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37372	12	Vanadium [V] as principal constituent	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37373	12	Rhodium [Rh] as principal constituent	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37376	12	Ruthenium [Ru] as principal constituent	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37378	12	Iridium [Ir] as principal constituent	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37379	12	Niobium [Nb] as principal constituent	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/3738	12	Molybdenum [Mo] as principal constituent	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37381	12	Tantalum [Ta] as principal constituent	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37383	12	Rhenium [Re] as principal constituent	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>

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D	H01L2224/37384	12	Tungsten [W] as principal constituent	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37386	10	with a principal constituent of the material being a non metallic, non metalloid inorganic material	<administrative transfer to H10W 72/625 and H10W 72/653 simultaneously>
D	H01L2224/37387	11	Ceramics, e.g. crystalline carbides, nitrides or oxides	<administrative transfer to H10W 72/625 and H10W 72/653 simultaneously>
D	H01L2224/37388	11	Glasses, e.g. amorphous oxides, nitrides or fluorides	<administrative transfer to H10W 72/625 and H10W 72/653 simultaneously>
D	H01L2224/3739	10	with a principal constituent of the material being a polymer, e.g. polyester, phenolic based polymer, epoxy	<administrative transfer to H10W 72/625 and H10W 72/653 simultaneously>
D	H01L2224/37391	11	The principal constituent being an elastomer, e.g. silicones, isoprene, neoprene	<administrative transfer to H10W 72/625 and H10W 72/653 simultaneously>
D	H01L2224/37393	10	with a principal constituent of the material being a solid not provided for in groups H01L2224/373 - H01L2224/37391, e.g. allotropes of carbon, fullerene, graphite, carbon-nanotubes, diamond	<administrative transfer to H10W 72/625 and H10W 72/653 simultaneously>
D	H01L2224/37394	10	with a principal constituent of the material being a liquid not provided for in groups H01L2224/373 - H01L2224/37391	<administrative transfer to H10W 72/625 and H10W 72/653 simultaneously>
D	H01L2224/37395	10	with a principal constituent of the material being a gas not provided for in groups H01L2224/373 - H01L2224/37391	<administrative transfer to H10W 72/625 and H10W 72/653 simultaneously>
D	H01L2224/37398	10	with a principal constituent of the material being a combination of two or more materials in the form of a matrix with a filler, i.e. being a hybrid material, e.g. segmented structures, foams	<administrative transfer to H10W 72/625 and H10W 72/653 simultaneously>
D	H01L2224/37399	9	Coating material	<administrative transfer to H10W 72/625, H10W 72/655 and H10W 72/651 simultaneously>
D	H01L2224/374	10	with a principal constituent of the material being a metal or a metalloid, e.g. boron [B], silicon [Si], germanium [Ge], arsenic [As],	<administrative transfer to H10W 72/625, H10W 72/655 and H10W 72/652 simultaneously>

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			antimony [Sb], tellurium [Te] and polonium [Po], and alloys thereof	
D	H01L2224/37401	11	the principal constituent melting at a temperature of less than 400°C	<administrative transfer to H10W 72/625, H10W 72/655 and H10W 72/652 simultaneously>
D	H01L2224/37405	12	Gallium [Ga] as principal constituent	<administrative transfer to H10W 72/625, H10W 72/655 and H10W 72/652 simultaneously>
D	H01L2224/37409	12	Indium [In] as principal constituent	<administrative transfer to H10W 72/625, H10W 72/655 and H10W 72/652 simultaneously>
D	H01L2224/37411	12	Tin [Sn] as principal constituent	<administrative transfer to H10W 72/625, H10W 72/655 and H10W 72/652 simultaneously>
D	H01L2224/37413	12	Bismuth [Bi] as principal constituent	<administrative transfer to H10W 72/625, H10W 72/655 and H10W 72/652 simultaneously>
D	H01L2224/37414	12	Thallium [Tl] as principal constituent	<administrative transfer to H10W 72/625, H10W 72/655 and H10W 72/652 simultaneously>
D	H01L2224/37416	12	Lead [Pb] as principal constituent	<administrative transfer to H10W 72/625, H10W 72/655 and H10W 72/652 simultaneously>
D	H01L2224/37417	11	the principal constituent melting at a temperature of greater than or equal to 400°C and less than 950°C	<administrative transfer to H10W 72/625, H10W 72/655 and H10W 72/652 simultaneously>
D	H01L2224/37418	12	Zinc [Zn] as principal constituent	<administrative transfer to H10W 72/625, H10W 72/655 and H10W 72/652 simultaneously>
D	H01L2224/3742	12	Antimony [Sb] as principal constituent	<administrative transfer to H10W 72/625, H10W 72/655 and H10W 72/652 simultaneously>
D	H01L2224/37423	12	Magnesium [Mg] as principal constituent	<administrative transfer to H10W 72/625, H10W 72/655 and H10W 72/652 simultaneously>
D	H01L2224/37424	12	Aluminium [Al] as principal constituent	<administrative transfer to H10W 72/625, H10W 72/655 and H10W 72/652 simultaneously>

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D	H01L2224/37438	11	the principal constituent melting at a temperature of greater than or equal to 950°C and less than 1550°C	<administrative transfer to H10W 72/625, H10W 72/655 and H10W 72/652 simultaneously>
D	H01L2224/37439	12	Silver [Ag] as principal constituent	<administrative transfer to H10W 72/625, H10W 72/655 and H10W 72/652 simultaneously>
D	H01L2224/37444	12	Gold [Au] as principal constituent	<administrative transfer to H10W 72/625, H10W 72/655 and H10W 72/652 simultaneously>
D	H01L2224/37447	12	Copper [Cu] as principal constituent	<administrative transfer to H10W 72/625, H10W 72/655 and H10W 72/652 simultaneously>
D	H01L2224/37449	12	Manganese [Mn] as principal constituent	<administrative transfer to H10W 72/625, H10W 72/655 and H10W 72/652 simultaneously>
D	H01L2224/37455	12	Nickel [Ni] as principal constituent	<administrative transfer to H10W 72/625, H10W 72/655 and H10W 72/652 simultaneously>
D	H01L2224/37457	12	Cobalt [Co] as principal constituent	<administrative transfer to H10W 72/625, H10W 72/655 and H10W 72/652 simultaneously>
D	H01L2224/3746	12	Iron [Fe] as principal constituent	<administrative transfer to H10W 72/625, H10W 72/655 and H10W 72/652 simultaneously>
D	H01L2224/37463	11	the principal constituent melting at a temperature of greater than 1550°C	<administrative transfer to H10W 72/625, H10W 72/655 and H10W 72/652 simultaneously>
D	H01L2224/37464	12	Palladium [Pd] as principal constituent	<administrative transfer to H10W 72/625, H10W 72/655 and H10W 72/652 simultaneously>
D	H01L2224/37466	12	Titanium [Ti] as principal constituent	<administrative transfer to H10W 72/625, H10W 72/655 and H10W 72/652 simultaneously>
D	H01L2224/37469	12	Platinum [Pt] as principal constituent	<administrative transfer to H10W 72/625, H10W 72/655 and H10W 72/652 simultaneously>
D	H01L2224/3747	12	Zirconium [Zr] as principal constituent	<administrative transfer to H10W 72/625, H10W

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				72/655 and H10W 72/652 simultaneously>
D	H01L2224/37471	12	Chromium [Cr] as principal constituent	<administrative transfer to H10W 72/625, H10W 72/655 and H10W 72/652 simultaneously>
D	H01L2224/37472	12	Vanadium [V] as principal constituent	<administrative transfer to H10W 72/625, H10W 72/655 and H10W 72/652 simultaneously>
D	H01L2224/37473	12	Rhodium [Rh] as principal constituent	<administrative transfer to H10W 72/625, H10W 72/655 and H10W 72/652 simultaneously>
D	H01L2224/37476	12	Ruthenium [Ru] as principal constituent	<administrative transfer to H10W 72/625, H10W 72/655 and H10W 72/652 simultaneously>
D	H01L2224/37478	12	Iridium [Ir] as principal constituent	<administrative transfer to H10W 72/625, H10W 72/655 and H10W 72/652 simultaneously>
D	H01L2224/37479	12	Niobium [Nb] as principal constituent	<administrative transfer to H10W 72/625, H10W 72/655 and H10W 72/652 simultaneously>
D	H01L2224/3748	12	Molybdenum [Mo] as principal constituent	<administrative transfer to H10W 72/625, H10W 72/655 and H10W 72/652 simultaneously>
D	H01L2224/37481	12	Tantalum [Ta] as principal constituent	<administrative transfer to H10W 72/625, H10W 72/655 and H10W 72/652 simultaneously>
D	H01L2224/37483	12	Rhenium [Re] as principal constituent	<administrative transfer to H10W 72/625, H10W 72/655 and H10W 72/652 simultaneously>
D	H01L2224/37484	12	Tungsten [W] as principal constituent	<administrative transfer to H10W 72/625, H10W 72/655 and H10W 72/652 simultaneously>
D	H01L2224/37486	10	with a principal constituent of the material being a non metallic, non metalloid inorganic material	<administrative transfer to H10W 72/625, H10W 72/655 and H10W 72/653 simultaneously>
D	H01L2224/37487	11	Ceramics, e.g. crystalline carbides, nitrides or oxides	<administrative transfer to H10W 72/625, H10W 72/655 and H10W 72/653 simultaneously>

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D	H01L2224/37488	11	Glasses, e.g. amorphous oxides, nitrides or fluorides	<administrative transfer to H10W 72/625, H10W 72/655 and H10W 72/653 simultaneously>
D	H01L2224/3749	10	with a principal constituent of the material being a polymer, e.g. polyester, phenolic based polymer, epoxy	<administrative transfer to H10W 72/625, H10W 72/655 and H10W 72/653 simultaneously>
D	H01L2224/37491	11	The principal constituent being an elastomer, e.g. silicones, isoprene, neoprene	<administrative transfer to H10W 72/625, H10W 72/655 and H10W 72/653 simultaneously>
D	H01L2224/37493	10	with a principal constituent of the material being a solid not provided for in groups H01L2224/374 - H01L2224/37491, e.g. allotropes of carbon, fullerene, graphite, carbon-nanotubes, diamond	<administrative transfer to H10W 72/625, H10W 72/655 and H10W 72/653 simultaneously>
D	H01L2224/37494	10	with a principal constituent of the material being a liquid not provided for in groups H01L2224/374 - H01L2224/37491	<administrative transfer to H10W 72/625, H10W 72/655 and H10W 72/653 simultaneously>
D	H01L2224/37495	10	with a principal constituent of the material being a gas not provided for in groups H01L2224/374 - H01L2224/37491	<administrative transfer to H10W 72/625, H10W 72/655 and H10W 72/653 simultaneously>
D	H01L2224/37498	10	with a principal constituent of the material being a combination of two or more materials in the form of a matrix with a filler, i.e. being a hybrid material, e.g. segmented structures, foams	<administrative transfer to H10W 72/625, H10W 72/655 and H10W 72/653 simultaneously>
D	H01L2224/37499	9	Shape or distribution of the fillers	<administrative transfer to H10W 72/625 and H10W 72/655 simultaneously>
D	H01L2224/3754	5	Coating	<administrative transfer to H10W 72/622>
D	H01L2224/37541	6	Structure	<administrative transfer to H10W 72/623>
D	H01L2224/3755	6	Shape	<administrative transfer to H10W 72/635>
D	H01L2224/3756	6	Disposition, e.g. coating on a part of the core	<administrative transfer to H10W 72/645>
D	H01L2224/37565	6	Single coating layer	<administrative transfer to H10W 72/622>
D	H01L2224/3757	6	Plural coating layers	<administrative transfer to H10W 72/623>
D	H01L2224/37572	7	Two-layer stack coating	<administrative transfer to H10W 72/623>
D	H01L2224/37573	7	Three-layer stack coating	<administrative transfer to H10W 72/623>

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D	H01L2224/37574	7	Four-layer stack coating	<administrative transfer to H10W 72/623>
D	H01L2224/37576	7	being mutually engaged together, e.g. through inserts	<administrative transfer to H10W 72/623>
D	H01L2224/37578	7	being disposed next to each other, e.g. side-to-side arrangements	<administrative transfer to H10W 72/623>
D	H01L2224/37599	6	Material	<administrative transfer to H10W 72/655>
D	H01L2224/376	7	with a principal constituent of the material being a metal or a metalloid, e.g. boron [B], silicon [Si], germanium [Ge], arsenic [As], antimony [Sb], tellurium [Te] and polonium [Po], and alloys thereof	<administrative transfer to H10W 72/655 and H10W 72/652 simultaneously>
D	H01L2224/37601	8	the principal constituent melting at a temperature of less than 400°C	<administrative transfer to H10W 72/655 and H10W 72/652 simultaneously>
D	H01L2224/37605	9	Gallium [Ga] as principal constituent	<administrative transfer to H10W 72/655 and H10W 72/652 simultaneously>
D	H01L2224/37609	9	Indium [In] as principal constituent	<administrative transfer to H10W 72/655 and H10W 72/652 simultaneously>
D	H01L2224/37611	9	Tin [Sn] as principal constituent	<administrative transfer to H10W 72/655 and H10W 72/652 simultaneously>
D	H01L2224/37613	9	Bismuth [Bi] as principal constituent	<administrative transfer to H10W 72/655 and H10W 72/652 simultaneously>
D	H01L2224/37614	9	Thallium [Tl] as principal constituent	<administrative transfer to H10W 72/655 and H10W 72/652 simultaneously>
D	H01L2224/37616	9	Lead [Pb] as principal constituent	<administrative transfer to H10W 72/655 and H10W 72/652 simultaneously>
D	H01L2224/37617	8	the principal constituent melting at a temperature of greater than or equal to 400°C and less than 950°C	<administrative transfer to H10W 72/655 and H10W 72/652 simultaneously>
D	H01L2224/37618	9	Zinc [Zn] as principal constituent	<administrative transfer to H10W 72/655 and H10W 72/652 simultaneously>

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D	H01L2224/3762	9	Antimony [Sb] as principal constituent	<administrative transfer to H10W 72/655 and H10W 72/652 simultaneously>
D	H01L2224/37623	9	Magnesium [Mg] as principal constituent	<administrative transfer to H10W 72/655 and H10W 72/652 simultaneously>
D	H01L2224/37624	9	Aluminium [Al] as principal constituent	<administrative transfer to H10W 72/655 and H10W 72/652 simultaneously>
D	H01L2224/37638	8	the principal constituent melting at a temperature of greater than or equal to 950°C and less than 1550°C	<administrative transfer to H10W 72/655 and H10W 72/652 simultaneously>
D	H01L2224/37639	9	Silver [Ag] as principal constituent	<administrative transfer to H10W 72/655 and H10W 72/652 simultaneously>
D	H01L2224/37644	9	Gold [Au] as principal constituent	<administrative transfer to H10W 72/655 and H10W 72/652 simultaneously>
D	H01L2224/37647	9	Copper [Cu] as principal constituent	<administrative transfer to H10W 72/655 and H10W 72/652 simultaneously>
D	H01L2224/37649	9	Manganese [Mn] as principal constituent	<administrative transfer to H10W 72/655 and H10W 72/652 simultaneously>
D	H01L2224/37655	9	Nickel [Ni] as principal constituent	<administrative transfer to H10W 72/655 and H10W 72/652 simultaneously>
D	H01L2224/37657	9	Cobalt [Co] as principal constituent	<administrative transfer to H10W 72/655 and H10W 72/652 simultaneously>
D	H01L2224/3766	9	Iron [Fe] as principal constituent	<administrative transfer to H10W 72/655 and H10W 72/652 simultaneously>
D	H01L2224/37663	8	the principal constituent melting at a temperature of greater than 1550°C	<administrative transfer to H10W 72/655 and H10W 72/652 simultaneously>
D	H01L2224/37664	9	Palladium [Pd] as principal constituent	<administrative transfer to H10W 72/655 and

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				H10W 72/652 simultaneously>
D	H01L2224/37666	9	Titanium [Ti] as principal constituent	<administrative transfer to H10W 72/655 and H10W 72/652 simultaneously>
D	H01L2224/37669	9	Platinum [Pt] as principal constituent	<administrative transfer to H10W 72/655 and H10W 72/652 simultaneously>
D	H01L2224/3767	9	Zirconium [Zr] as principal constituent	<administrative transfer to H10W 72/655 and H10W 72/652 simultaneously>
D	H01L2224/37671	9	Chromium [Cr] as principal constituent	<administrative transfer to H10W 72/655 and H10W 72/652 simultaneously>
D	H01L2224/37672	9	Vanadium [V] as principal constituent	<administrative transfer to H10W 72/655 and H10W 72/652 simultaneously>
D	H01L2224/37673	9	Rhodium [Rh] as principal constituent	<administrative transfer to H10W 72/655 and H10W 72/652 simultaneously>
D	H01L2224/37676	9	Ruthenium [Ru] as principal constituent	<administrative transfer to H10W 72/655 and H10W 72/652 simultaneously>
D	H01L2224/37678	9	Iridium [Ir] as principal constituent	<administrative transfer to H10W 72/655 and H10W 72/652 simultaneously>
D	H01L2224/37679	9	Niobium [Nb] as principal constituent	<administrative transfer to H10W 72/655 and H10W 72/652 simultaneously>
D	H01L2224/3768	9	Molybdenum [Mo] as principal constituent	<administrative transfer to H10W 72/655 and H10W 72/652 simultaneously>
D	H01L2224/37681	9	Tantalum [Ta] as principal constituent	<administrative transfer to H10W 72/655 and H10W 72/652 simultaneously>
D	H01L2224/37683	9	Rhenium [Re] as principal constituent	<administrative transfer to H10W 72/655 and H10W 72/652 simultaneously>

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D	H01L2224/37684	9	Tungsten [W] as principal constituent	<administrative transfer to H10W 72/655 and H10W 72/652 simultaneously>
D	H01L2224/37686	7	with a principal constituent of the material being a non metallic, non metalloid inorganic material	<administrative transfer to H10W 72/655 and H10W 72/653 simultaneously>
D	H01L2224/37687	8	Ceramics, e.g. crystalline carbides, nitrides or oxides	<administrative transfer to H10W 72/655 and H10W 72/653 simultaneously>
D	H01L2224/37688	8	Glasses, e.g. amorphous oxides, nitrides or fluorides	<administrative transfer to H10W 72/655 and H10W 72/653 simultaneously>
D	H01L2224/3769	7	with a principal constituent of the material being a polymer, e.g. polyester, phenolic based polymer, epoxy	<administrative transfer to H10W 72/655 and H10W 72/653 simultaneously>
D	H01L2224/37691	8	The principal constituent being an elastomer, e.g. silicones, isoprene, neoprene	<administrative transfer to H10W 72/655 and H10W 72/653 simultaneously>
D	H01L2224/37693	7	with a principal constituent of the material being a solid not provided for in groups H01L2224/376 - H01L2224/37691, e.g. allotropes of carbon, fullerene, graphite, carbon-nanotubes, diamond	<administrative transfer to H10W 72/655 and H10W 72/653 simultaneously>
D	H01L2224/37694	7	with a principal constituent of the material being a liquid not provided for in groups H01L2224/376 - H01L2224/37691	<administrative transfer to H10W 72/655 and H10W 72/653 simultaneously>
D	H01L2224/37695	7	with a principal constituent of the material being a gas not provided for in groups H01L2224/376 - H01L2224/37691	<administrative transfer to H10W 72/655 and H10W 72/653 simultaneously>
D	H01L2224/37698	7	with a principal constituent of the material being a combination of two or more materials in the form of a matrix with a filler, i.e. being a hybrid material, e.g. segmented structures, foams	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/651 simultaneously>
D	H01L2224/37699	8	Material of the matrix	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/651 simultaneously>
D	H01L2224/377	9	with a principal constituent of the material being a metal or a metalloid, e.g. boron [B], silicon [Si], germanium [Ge], arsenic [As],	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>

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			antimony [Sb], tellurium [Te] and polonium [Po], and alloys thereof	
D	H01L2224/37701	10	the principal constituent melting at a temperature of less than 400°C	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37705	11	Gallium [Ga] as principal constituent	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37709	11	Indium [In] as principal constituent	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37711	11	Tin [Sn] as principal constituent	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37713	11	Bismuth [Bi] as principal constituent	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37714	11	Thallium [Tl] as principal constituent	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37716	11	Lead [Pb] as principal constituent	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37717	10	the principal constituent melting at a temperature of greater than or equal to 400°C and less than 950°C	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37718	11	Zinc [Zn] as principal constituent	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/3772	11	Antimony [Sb] as principal constituent	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37723	11	Magnesium [Mg] as principal constituent	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37724	11	Aluminium [Al] as principal constituent	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>

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D	H01L2224/37738	10	the principal constituent melting at a temperature of greater than or equal to 950°C and less than 1550°C	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37739	11	Silver [Ag] as principal constituent	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37744	11	Gold [Au] as principal constituent	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37747	11	Copper [Cu] as principal constituent	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37749	11	Manganese [Mn] as principal constituent	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37755	11	Nickel [Ni] as principal constituent	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37757	11	Cobalt [Co] as principal constituent	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/3776	11	Iron [Fe] as principal constituent	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37763	10	the principal constituent melting at a temperature of greater than 1550°C	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37764	11	Palladium [Pd] as principal constituent	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37766	11	Titanium [Ti] as principal constituent	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37769	11	Platinum [Pt] as principal constituent	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/3777	11	Zirconium [Zr] as principal constituent	<administrative transfer to H10W 72/655, H10W

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				72/625 and H10W 72/652 simultaneously>
D	H01L2224/37771	11	Chromium [Cr] as principal constituent	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37772	11	Vanadium [V] as principal constituent	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37773	11	Rhodium [Rh] as principal constituent	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37776	11	Ruthenium [Ru] as principal constituent	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37778	11	Iridium [Ir] as principal constituent	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37779	11	Niobium [Nb] as principal constituent	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/3778	11	Molybdenum [Mo] as principal constituent	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37781	11	Tantalum [Ta] as principal constituent	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37783	11	Rhenium [Re] as principal constituent	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37784	11	Tungsten [W] as principal constituent	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37786	9	with a principal constituent of the material being a non metallic, non metalloid inorganic material	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/653 simultaneously>
D	H01L2224/37787	10	Ceramics, e.g. crystalline carbides, nitrides or oxides	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/653 simultaneously>

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D	H01L2224/37788	10	Glasses, e.g. amorphous oxides, nitrides or fluorides	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/653 simultaneously>
D	H01L2224/3779	9	with a principal constituent of the material being a polymer, e.g. polyester, phenolic based polymer, epoxy	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/653 simultaneously>
D	H01L2224/37791	10	The principal constituent being an elastomer, e.g. silicones, isoprene, neoprene	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/653 simultaneously>
D	H01L2224/37793	9	with a principal constituent of the material being a solid not provided for in groups H01L2224/377 - H01L2224/37791, e.g. allotropes of carbon, fullerene, graphite, carbon-nanotubes, diamond	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/653 simultaneously>
D	H01L2224/37794	9	with a principal constituent of the material being a liquid not provided for in groups H01L2224/377 - H01L2224/37791	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/653 simultaneously>
D	H01L2224/37795	9	with a principal constituent of the material being a gas not provided for in groups H01L2224/377 - H01L2224/37791	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/653 simultaneously>
D	H01L2224/37798	8	Fillers	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/651 simultaneously>
D	H01L2224/37799	9	Base material	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/651 simultaneously>
D	H01L2224/378	10	with a principal constituent of the material being a metal or a metalloid, e.g. boron [B], silicon [Si], germanium [Ge], arsenic [As], antimony [Sb], tellurium [Te] and polonium [Po], and alloys thereof	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37801	11	the principal constituent melting at a temperature of less than 400°C	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37805	12	Gallium [Ga] as principal constituent	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37809	12	Indium [In] as principal constituent	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>

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D	H01L2224/37811	12	Tin [Sn] as principal constituent	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37813	12	Bismuth [Bi] as principal constituent	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37814	12	Thallium [Tl] as principal constituent	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37816	12	Lead [Pb] as principal constituent	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37817	11	the principal constituent melting at a temperature of greater than or equal to 400°C and less than 950°C	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37818	12	Zinc [Zn] as principal constituent	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/3782	12	Antimony [Sb] as principal constituent	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37823	12	Magnesium [Mg] as principal constituent	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37824	12	Aluminium [Al] as principal constituent	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37838	11	the principal constituent melting at a temperature of greater than or equal to 950°C and less than 1550°C	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37839	12	Silver [Ag] as principal constituent	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37844	12	Gold [Au] as principal constituent	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37847	12	Copper [Cu] as principal constituent	<administrative transfer to H10W 72/655, H10W

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				72/625 and H10W 72/652 simultaneously>
D	H01L2224/37849	12	Manganese [Mn] as principal constituent	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37855	12	Nickel [Ni] as principal constituent	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37857	12	Cobalt [Co] as principal constituent	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/3786	12	Iron [Fe] as principal constituent	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37863	11	the principal constituent melting at a temperature of greater than 1550°C	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37864	12	Palladium [Pd] as principal constituent	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37866	12	Titanium [Ti] as principal constituent	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37869	12	Platinum [Pt] as principal constituent	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/3787	12	Zirconium [Zr] as principal constituent	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37871	12	Chromium [Cr] as principal constituent	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37872	12	Vanadium [V] as principal constituent	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37873	12	Rhodium [Rh] as principal constituent	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>

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D	H01L2224/37876	12	Ruthenium [Ru] as principal constituent	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37878	12	Iridium [Ir] as principal constituent	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37879	12	Niobium [Nb] as principal constituent	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/3788	12	Molybdenum [Mo] as principal constituent	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37881	12	Tantalum [Ta] as principal constituent	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37883	12	Rhenium [Re] as principal constituent	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37884	12	Tungsten [W] as principal constituent	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37886	10	with a principal constituent of the material being a non metallic, non metalloid inorganic material	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/653 simultaneously>
D	H01L2224/37887	11	Ceramics, e.g. crystalline carbides, nitrides or oxides	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/653 simultaneously>
D	H01L2224/37888	11	Glasses, e.g. amorphous oxides, nitrides or fluorides	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/653 simultaneously>
D	H01L2224/3789	10	with a principal constituent of the material being a polymer, e.g. polyester, phenolic based polymer, epoxy	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/653 simultaneously>
D	H01L2224/37891	11	The principal constituent being an elastomer, e.g. silicones, isoprene, neoprene	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/653 simultaneously>
D	H01L2224/37893	10	with a principal constituent of the material being a solid not provided for in groups	<administrative transfer to H10W 72/655, H10W

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			H01L2224/378 - H01L2224/37891, e.g. allotropes of carbon, fullerene, graphite, carbon-nanotubes, diamond	72/625 and H10W 72/653 simultaneously>
D	H01L2224/37894	10	with a principal constituent of the material being a liquid not provided for in groups H01L2224/378 - H01L2224/37891	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/653 simultaneously>
D	H01L2224/37895	10	with a principal constituent of the material being a gas not provided for in groups H01L2224/378 - H01L2224/37891	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/653 simultaneously>
D	H01L2224/37898	10	with a principal constituent of the material being a combination of two or more materials in the form of a matrix with a filler, i.e. being a hybrid material, e.g. segmented structures, foams	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/651 simultaneously>
D	H01L2224/37899	9	Coating material	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/651 simultaneously>
D	H01L2224/379	10	with a principal constituent of the material being a metal or a metalloid, e.g. boron [B], silicon [Si], germanium [Ge], arsenic [As], antimony [Sb], tellurium [Te] and polonium [Po], and alloys thereof	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37901	11	the principal constituent melting at a temperature of less than 400°C	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37905	12	Gallium [Ga] as principal constituent	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37909	12	Indium [In] as principal constituent	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37911	12	Tin [Sn] as principal constituent	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37913	12	Bismuth [Bi] as principal constituent	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37914	12	Thallium [Tl] as principal constituent	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>

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D	H01L2224/37916	12	Lead [Pb] as principal constituent	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37917	11	the principal constituent melting at a temperature of greater than or equal to 400°C and less than 950°C	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37918	12	Zinc [Zn] as principal constituent	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/3792	12	Antimony [Sb] as principal constituent	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37923	12	Magnesium [Mg] as principal constituent	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37924	12	Aluminium [Al] as principal constituent	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37938	11	the principal constituent melting at a temperature of greater than or equal to 950°C and less than 1550°C	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37939	12	Silver [Ag] as principal constituent	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37944	12	Gold [Au] as principal constituent	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37947	12	Copper [Cu] as principal constituent	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37949	12	Manganese [Mn] as principal constituent	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37955	12	Nickel [Ni] as principal constituent	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37957	12	Cobalt [Co] as principal constituent	<administrative transfer to H10W 72/655, H10W

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				72/625 and H10W 72/652 simultaneously>
D	H01L2224/3796	12	Iron [Fe] as principal constituent	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37963	11	the principal constituent melting at a temperature of greater than 1550°C	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37964	12	Palladium [Pd] as principal constituent	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37966	12	Titanium [Ti] as principal constituent	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37969	12	Platinum [Pt] as principal constituent	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/3797	12	Zirconium [Zr] as principal constituent	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37971	12	Chromium [Cr] as principal constituent	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37972	12	Vanadium [V] as principal constituent	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37973	12	Rhodium [Rh] as principal constituent	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37976	12	Ruthenium [Ru] as principal constituent	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37978	12	Iridium [Ir] as principal constituent	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37979	12	Niobium [Nb] as principal constituent	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>

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D	H01L2224/3798	12	Molybdenum [Mo] as principal constituent	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37981	12	Tantalum [Ta] as principal constituent	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37983	12	Rhenium [Re] as principal constituent	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37984	12	Tungsten [W] as principal constituent	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L2224/37986	10	with a principal constituent of the material being a non metallic, non metalloid inorganic material	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/653 simultaneously>
D	H01L2224/37987	11	Ceramics, e.g. crystalline carbides, nitrides or oxides	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/653 simultaneously>
D	H01L2224/37988	11	Glasses, e.g. amorphous oxides, nitrides or fluorides	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/653 simultaneously>
D	H01L2224/3799	10	with a principal constituent of the material being a polymer, e.g. polyester, phenolic based polymer, epoxy	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/653 simultaneously>
D	H01L2224/37991	11	The principal constituent being an elastomer, e.g. silicones, isoprene, neoprene	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/653 simultaneously>
D	H01L2224/37993	10	with a principal constituent of the material being a solid not provided for in groups H01L2224/379 - H01L2224/37991, e.g. allotropes of carbon, fullerene, graphite, carbon-nanotubes, diamond	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/653 simultaneously>
D	H01L2224/37994	10	with a principal constituent of the material being a liquid not provided for in groups H01L2224/379 - H01L2224/37991	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/653 simultaneously>
D	H01L2224/37995	10	with a principal constituent of the material being a gas not provided for in groups H01L2224/379 - H01L2224/37991	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/653 simultaneously>

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D	H01L2224/37998	10	with a principal constituent of the material being a combination of two or more materials in the form of a matrix with a filler, i.e. being a hybrid material, e.g. segmented structures, foams	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/653 simultaneously>
D	H01L2224/37999	9	Shape or distribution of the fillers	<administrative transfer to H10W 72/655 and H10W 72/625 simultaneously>
D	H01L2224/38	4	of a plurality of strap connectors	<administrative transfer to H10W 72/60>
D	H01L2224/39	3	Structure, shape, material or disposition of the strap connectors after the connecting process	<administrative transfer to H10W 72/60 and H10W 72/07651 simultaneously>
D	H01L2224/40	4	of an individual strap connector	<administrative transfer to H10W 72/60 and H10W 72/07651 simultaneously>
D	H01L2224/4001	5	Structure	<administrative transfer to H10W 72/07652 and H10W 72/621 simultaneously>
D	H01L2224/4005	5	Shape	<administrative transfer to H10W 72/07653 and H10W 72/631 simultaneously>
D	H01L2224/4007	6	of bonding interfaces, e.g. interlocking features	<administrative transfer to H10W 72/07653 and H10W 72/631 simultaneously>
D	H01L2224/4009	6	Loop shape	<administrative transfer to H10W 72/07653 and H10W 72/631 simultaneously>
D	H01L2224/40091	7	Arched	<administrative transfer to H10W 72/07653>
D	H01L2224/40095	7	Kinked	<administrative transfer to H10W 72/07653>
D	H01L2224/401	5	Disposition	<administrative transfer to H10W 72/647>
D	H01L2224/40101	6	Connecting bonding areas at the same height, e.g. horizontal bond	<administrative transfer to H10W 72/647>
D	H01L2224/40105	6	Connecting bonding areas at different heights	<administrative transfer to H10W 72/647>
D	H01L2224/40106	7	the connector being orthogonal to a side surface of the semiconductor or solid-state body, e.g. parallel layout	<administrative transfer to H10W 72/642>

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D	H01L2224/40108	7	the connector not being orthogonal to a side surface of the semiconductor or solid-state body, e.g. fanned-out connectors, radial layout	<administrative transfer to H10W 72/643>
D	H01L2224/40111	7	the strap connector extending above another semiconductor or solid-state body	<administrative transfer to H10W 72/07654>
D	H01L2224/4013	6	Connecting within a semiconductor or solid-state body, i.e. fly strap, bridge strap	<administrative transfer to H10W 72/644>
D	H01L2224/40132	7	with an intermediate bond, e.g. continuous strap daisy chain	<administrative transfer to H10W 72/644>
D	H01L2224/40135	6	Connecting between different semiconductor or solid-state bodies, i.e. chip-to-chip	<administrative transfer to H10W 90/761>
D	H01L2224/40137	7	the bodies being arranged next to each other, e.g. on a common substrate	<administrative transfer to H10W 90/763>
D	H01L2224/40139	8	with an intermediate bond, e.g. continuous strap daisy chain	<administrative transfer to H10W 90/763>
D	H01L2224/40141	7	the bodies being arranged on opposite sides of a substrate, e.g. mirror arrangements	<administrative transfer to H10W 90/761>
D	H01L2224/40145	7	the bodies being stacked	<administrative transfer to H10W 90/762>
D	H01L2224/40147	8	with an intermediate bond, e.g. continuous strap daisy chain	<administrative transfer to H10W 90/762>
D	H01L2224/40151	6	Connecting between a semiconductor or solid-state body and an item not being a semiconductor or solid-state body, e.g. chip-to-substrate, chip-to-passive	<administrative transfer to H10W 90/761>
D	H01L2224/40153	7	the body and the item being arranged next to each other, e.g. on a common substrate	<administrative transfer to H10W 90/761>
D	H01L2224/40155	8	the item being non-metallic, e.g. insulating substrate with or without metallisation	<administrative transfer to H10W 90/765>
D	H01L2224/40157	9	Connecting the strap to a bond pad of the item	<administrative transfer to H10W 90/765>
D	H01L2224/40158	10	the bond pad being disposed in a recess of the surface of the item	<administrative transfer to H10W 90/765>
D	H01L2224/40159	10	the bond pad protruding from the surface of the item	<administrative transfer to H10W 90/765>
D	H01L2224/4016	9	Connecting the strap to a pin of the item	<administrative transfer to H10W 90/765>
D	H01L2224/40163	9	Connecting the strap to a potential ring of the item	<administrative transfer to H10W 90/765>
D	H01L2224/40165	9	Connecting the strap to a via metallisation of the item	<administrative transfer to H10W 90/765>
D	H01L2224/40175	8	the item being metallic	<administrative transfer to H10W 90/767>
D	H01L2224/40177	9	Connecting the strap to a bond pad of the item	<administrative transfer to H10W 90/767>
D	H01L2224/40178	10	the bond pad being disposed in a recess of the surface of the item	<administrative transfer to H10W 90/767>

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D	H01L2224/40179	10	the bond pad protruding from the surface of the item	<administrative transfer to H10W 90/767>
D	H01L2224/40183	9	Connecting the strap to a potential ring of the item	<administrative transfer to H10W 90/767>
D	H01L2224/40195	8	the item being a discrete passive component	<administrative transfer to H10W 90/769>
D	H01L2224/40221	7	the body and the item being stacked	<administrative transfer to H10W 90/761>
D	H01L2224/40225	8	the item being non-metallic, e.g. insulating substrate with or without metallisation	<administrative transfer to H10W 90/764>
D	H01L2224/40227	9	Connecting the strap to a bond pad of the item	<administrative transfer to H10W 90/764>
D	H01L2224/40228	10	the bond pad being disposed in a recess of the surface of the item	<administrative transfer to H10W 90/764>
D	H01L2224/40229	10	the bond pad protruding from the surface of the item	<administrative transfer to H10W 90/764>
D	H01L2224/4023	9	Connecting the strap to a pin of the item	<administrative transfer to H10W 90/764>
D	H01L2224/40233	9	Connecting the strap to a potential ring of the item	<administrative transfer to H10W 90/764>
D	H01L2224/40235	9	Connecting the strap to a via metallisation of the item	<administrative transfer to H10W 90/764>
D	H01L2224/40237	9	Connecting the strap to a die pad of the item	<administrative transfer to H10W 90/764>
D	H01L2224/4024	9	Connecting between the body and an opposite side of the item with respect to the body	<administrative transfer to H10W 90/764>
D	H01L2224/40245	8	the item being metallic	<administrative transfer to H10W 90/766>
D	H01L2224/40247	9	Connecting the strap to a bond pad of the item	<administrative transfer to H10W 90/766>
D	H01L2224/40248	10	the bond pad being disposed in a recess of the surface of the item	<administrative transfer to H10W 90/766>
D	H01L2224/40249	10	the bond pad protruding from the surface of the item	<administrative transfer to H10W 90/766>
D	H01L2224/40253	9	Connecting the strap to a potential ring of the item	<administrative transfer to H10W 90/766>
D	H01L2224/40257	9	Connecting the strap to a die pad of the item	<administrative transfer to H10W 90/766>
D	H01L2224/4026	9	Connecting between the body and an opposite side of the item with respect to the body	<administrative transfer to H10W 90/766>
D	H01L2224/40265	8	the item being a discrete passive component	<administrative transfer to H10W 90/768>
D	H01L2224/404	5	Connecting portions	<administrative transfer to H10W 72/60>
D	H01L2224/4046	6	with multiple bonds on the same bonding area	<administrative transfer to H10W 72/07653>
D	H01L2224/40475	6	connected to auxiliary connecting means on the bonding areas	<administrative transfer to H10W 72/646>

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D	H01L2224/40477	7	being a pre-ball (i.e. a ball formed by capillary bonding)	<administrative transfer to H10W 72/646>
D	H01L2224/40479	8	on the semiconductor or solid-state body	<administrative transfer to H10W 72/646>
D	H01L2224/4048	8	outside the semiconductor or solid-state body	<administrative transfer to H10W 72/646>
D	H01L2224/40484	8	being a plurality of pre-balls disposed side-to-side	<administrative transfer to H10W 72/646>
D	H01L2224/40486	9	on the semiconductor or solid-state body	<administrative transfer to H10W 72/646>
D	H01L2224/40487	9	outside the semiconductor or solid-state body	<administrative transfer to H10W 72/646>
D	H01L2224/40491	7	being an additional member attached to the bonding area through an adhesive or solder, e.g. buffer pad	<administrative transfer to H10W 72/646>
D	H01L2224/40496	7	not being interposed between the connector and the bonding area	<administrative transfer to H10W 72/646>
D	H01L2224/40499	7	Material of the auxiliary connecting means	<administrative transfer to H10W 72/646>
D	H01L2224/405	5	Material	<administrative transfer to H10W 72/07655>
D	H01L2224/40505	6	at the bonding interface	<administrative transfer to H10W 72/07655>
D	H01L2224/40506	7	comprising an eutectic alloy	<administrative transfer to H10W 72/07655 and H10W 72/6524 simultaneously>
D	H01L2224/40507	7	comprising an intermetallic compound	<administrative transfer to H10W 72/6528>
D	H01L2224/4051	7	Morphology of the connecting portion, e.g. grain size distribution	<administrative transfer to H10W 72/07655>
D	H01L2224/4052	7	Bonding interface between the connecting portion and the bonding area	<administrative transfer to H10W 72/07655>
D	H01L2224/4099	5	Auxiliary members for strap connectors, e.g. flow-barriers, spacers	<administrative transfer to H10W 72/681>
D	H01L2224/40991	6	being formed on the semiconductor or solid-state body to be connected	<administrative transfer to H10W 72/681>
D	H01L2224/40992	7	Reinforcing structures	<administrative transfer to H10W 72/683>
D	H01L2224/40993	7	Alignment aids	<administrative transfer to H10W 72/685>
D	H01L2224/40996	6	being formed on an item to be connected not being a semiconductor or solid-state body	<administrative transfer to H10W 72/681>
D	H01L2224/40997	7	Reinforcing structures	<administrative transfer to H10W 72/683>
D	H01L2224/40998	7	Alignment aids	<administrative transfer to H10W 72/685>

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D	H01L2224/41	4	of a plurality of strap connectors	<administrative transfer to H10W 72/60>
D	H01L2224/4101	5	Structure	<administrative transfer to H10W 72/627 and H10W 72/07652 simultaneously>
D	H01L2224/4103	6	Connectors having different sizes	<administrative transfer to H10W 72/627 and H10W 72/07652 simultaneously>
D	H01L2224/4105	5	Shape	<administrative transfer to H10W 72/631>
D	H01L2224/41051	6	Connectors having different shapes	<administrative transfer to H10W 72/637>
D	H01L2224/41052	7	Different loop heights	<administrative transfer to H10W 72/637>
D	H01L2224/411	5	Disposition	<administrative transfer to H10W 72/647>
D	H01L2224/41105	6	Connecting at different heights	<administrative transfer to H10W 72/647>
D	H01L2224/41107	7	on the semiconductor or solid-state body being	<administrative transfer to H10W 72/647>
D	H01L2224/41109	7	outside the semiconductor or solid-state body	<administrative transfer to H10W 72/647>
D	H01L2224/4111	6	the connectors being bonded to at least one common bonding area, e.g. daisy chain	<administrative transfer to H10W 72/647 and H10W 72/6478 simultaneously>
D	H01L2224/41111	7	the connectors connecting two common bonding areas	<administrative transfer to H10W 72/647 and H10W 72/6478 simultaneously>
D	H01L2224/41112	7	the connectors connecting a common bonding area on the semiconductor or solid-state body to different bonding areas outside the body, e.g. diverging straps	<administrative transfer to H10W 72/647 and H10W 72/6478 simultaneously>
D	H01L2224/41113	7	the connectors connecting different bonding areas on the semiconductor or solid-state body to a common bonding area outside the body, e.g. converging straps	<administrative transfer to H10W 72/647 and H10W 72/6478 simultaneously>
D	H01L2224/4112	6	Layout	<administrative transfer to H10W 72/647 and H10W 72/07654 simultaneously>
D	H01L2224/4117	7	Crossed straps	<administrative transfer to H10W 72/647 and H10W 72/07654 simultaneously>

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D	H01L2224/41171	7	Fan-out arrangements	<administrative transfer to H10W 72/647 and H10W 72/643 simultaneously>
D	H01L2224/41173	8	Radial fan-out arrangements	<administrative transfer to H10W 72/647 and H10W 72/643 simultaneously>
D	H01L2224/41174	7	Stacked arrangements	<administrative transfer to H10W 72/647 and H10W 72/07654 simultaneously>
D	H01L2224/41175	7	Parallel arrangements	<administrative transfer to H10W 72/647 and H10W 72/642 simultaneously>
D	H01L2224/41176	8	Strap connectors having the same loop shape and height	<administrative transfer to H10W 72/647 and H10W 72/642 simultaneously>
D	H01L2224/41177	7	Combinations of different arrangements	<administrative transfer to H10W 72/647 and H10W 72/07654 simultaneously>
D	H01L2224/41179	7	Corner adaptations, i.e. disposition of the strap connectors at the corners of the semiconductor or solid-state body	<administrative transfer to H10W 72/647 and H10W 72/07654 simultaneously>
D	H01L2224/4118	6	being disposed on at least two different sides of the body, e.g. dual array	<administrative transfer to H10W 72/647 and H10W 72/07654 simultaneously>
D	H01L2224/414	5	Connecting portions	<administrative transfer to H10W 72/60>
D	H01L2224/4141	6	the connecting portions being stacked	<administrative transfer to H10W 72/647 and H10W 72/646 simultaneously>
D	H01L2224/41421	7	on the semiconductor or solid-state body	<administrative transfer to H10W 72/647 and H10W 72/646 simultaneously>
D	H01L2224/41422	7	outside the semiconductor or solid-state body	<administrative transfer to H10W 72/647 and H10W 72/646 simultaneously>
D	H01L2224/4143	6	the connecting portions being staggered	<administrative transfer to H10W 72/647 and H10W 72/07654 simultaneously>

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D	H01L2224/415	5	Material	<administrative transfer to H10W 72/07655>
D	H01L2224/41505	6	Connectors having different materials	<administrative transfer to H10W 72/07655 and H10W 72/657 simultaneously>
D	H01L2224/42	2	Wire connectors; Manufacturing methods related thereto	<administrative transfer to H10W 72/50>
D	H01L2224/43	3	Manufacturing methods	<administrative transfer to H10W 72/015>
D	H01L2224/43001	4	Involving a temporary auxiliary member not forming part of the manufacturing apparatus, e.g. removable or sacrificial coating, film or substrate	<administrative transfer to H10W 72/01504>
D	H01L2224/431	4	Pre-treatment of the preform connector	<administrative transfer to H10W 72/015>
D	H01L2224/4312	5	Applying permanent coating, e.g. in-situ coating	<administrative transfer to H10W 72/01515>
D	H01L2224/43125	6	Plating, e.g. electroplating, electroless plating	<administrative transfer to H10W 72/01515>
D	H01L2224/432	4	Mechanical processes	<administrative transfer to H10W 72/015>
D	H01L2224/4321	5	Pulling	<administrative transfer to H10W 72/01551>
D	H01L2224/435	4	Modification of a pre-existing material	<administrative transfer to H10W 72/01561>
D	H01L2224/4351	5	Sintering	<administrative transfer to H10W 72/01561>
D	H01L2224/4352	5	Anodisation	<administrative transfer to H10W 72/01561>
D	H01L2224/437	4	Involving monitoring, e.g. feedback loop	<administrative transfer to H10W 72/015>
D	H01L2224/438	4	Post-treatment of the connector	<administrative transfer to H10W 72/015>
D	H01L2224/4381	5	Cleaning, e.g. oxide removal step, desmearing	<administrative transfer to H10W 72/01571>
D	H01L2224/4382	5	Applying permanent coating, e.g. in-situ coating	<administrative transfer to H10W 72/01515>
D	H01L2224/43821	6	Spray coating	<administrative transfer to H10W 72/01515>
D	H01L2224/43822	6	Dip coating	<administrative transfer to H10W 72/01515>
D	H01L2224/43823	6	Immersion coating, e.g. solder bath	<administrative transfer to H10W 72/01515>
D	H01L2224/43824	6	Chemical solution deposition [CSD], i.e. using a liquid precursor	<administrative transfer to H10W 72/01515>
D	H01L2224/43825	6	Plating, e.g. electroplating, electroless plating	<administrative transfer to H10W 72/01515>

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D	H01L2224/43826	6	Physical vapour deposition [PVD], e.g. evaporation, sputtering	<administrative transfer to H10W 72/01515>
D	H01L2224/43827	6	Chemical vapour deposition [CVD], e.g. laser CVD	<administrative transfer to H10W 72/01515>
D	H01L2224/4383	5	Reworking	<administrative transfer to H10W 72/01551>
D	H01L2224/43831	6	with a chemical process, e.g. with etching of the connector	<administrative transfer to H10W 72/01553>
D	H01L2224/43847	6	with a mechanical process, e.g. with flattening of the connector	<administrative transfer to H10W 72/01561>
D	H01L2224/43848	5	Thermal treatments, e.g. annealing, controlled cooling	<administrative transfer to H10W 72/01565>
D	H01L2224/43985	4	Methods of manufacturing wire connectors involving a specific sequence of method steps	<administrative transfer to H10W 72/015>
D	H01L2224/43986	5	with repetition of the same manufacturing step	<administrative transfer to H10W 72/015>
D	H01L2224/44	3	Structure, shape, material or disposition of the wire connectors prior to the connecting process	<administrative transfer to H10W 72/50>
D	H01L2224/45	4	of an individual wire connector	<administrative transfer to H10W 72/50>
D	H01L2224/45001	5	Core members of the connector	<administrative transfer to H10W 72/50>
D	H01L2224/45005	6	Structure	<administrative transfer to H10W 72/521>
D	H01L2224/4501	6	Shape	<administrative transfer to H10W 72/531>
D	H01L2224/45012	7	Cross-sectional shape	<administrative transfer to H10W 72/533>
D	H01L2224/45013	8	being non uniform along the connector	<administrative transfer to H10W 72/533>
D	H01L2224/45014	8	Ribbon connectors, e.g. rectangular cross-section	<administrative transfer to H10W 72/534>
D	H01L2224/45015	8	being circular	<no transfer>
D	H01L2224/45016	8	being elliptic	<administrative transfer to H10W 72/533>
D	H01L2224/4502	6	Disposition	<administrative transfer to H10W 72/541>
D	H01L2224/45025	6	Plural core members	<administrative transfer to H10W 72/524>
D	H01L2224/45026	7	being mutually engaged together, e.g. through inserts	<administrative transfer to H10W 72/524>
D	H01L2224/45028	7	Side-to-side arrangements	<administrative transfer to H10W 72/524>
D	H01L2224/4503	7	Stacked arrangements	<administrative transfer to H10W 72/522>
D	H01L2224/45032	8	Two-layer arrangements	<administrative transfer to H10W 72/522>

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D	H01L2224/45033	8	Three-layer arrangements	<administrative transfer to H10W 72/522>
D	H01L2224/45034	8	Four-layer arrangements	<administrative transfer to H10W 72/522>
D	H01L2224/45099	6	Material	<administrative transfer to H10W 72/551>
D	H01L2224/451	7	with a principal constituent of the material being a metal or a metalloid, e.g. boron (B), silicon (Si), germanium (Ge), arsenic (As), antimony (Sb), tellurium (Te) and polonium (Po), and alloys thereof	<administrative transfer to H10W 72/552>
D	H01L2224/45101	8	the principal constituent melting at a temperature of less than 400°C	<administrative transfer to H10W 72/552>
D	H01L2224/45105	9	Gallium (Ga) as principal constituent	<administrative transfer to H10W 72/552>
D	H01L2224/45109	9	Indium (In) as principal constituent	<administrative transfer to H10W 72/552>
D	H01L2224/45111	9	Tin (Sn) as principal constituent	<administrative transfer to H10W 72/552>
D	H01L2224/45113	9	Bismuth (Bi) as principal constituent	<administrative transfer to H10W 72/552>
D	H01L2224/45114	9	Thallium (Tl) as principal constituent	<administrative transfer to H10W 72/552>
D	H01L2224/45116	9	Lead (Pb) as principal constituent	<administrative transfer to H10W 72/552>
D	H01L2224/45117	8	the principal constituent melting at a temperature of greater than or equal to 400°C and less than 950°C	<administrative transfer to H10W 72/552>
D	H01L2224/45118	9	Zinc (Zn) as principal constituent	<administrative transfer to H10W 72/552>
D	H01L2224/4512	9	Antimony (Sb) as principal constituent	<administrative transfer to H10W 72/552>
D	H01L2224/45123	9	Magnesium (Mg) as principal constituent	<administrative transfer to H10W 72/552>
D	H01L2224/45124	9	Aluminium (Al) as principal constituent	<administrative transfer to H10W 72/5524>
D	H01L2224/45138	8	the principal constituent melting at a temperature of greater than or equal to 950°C and less than 1550°C	<administrative transfer to H10W 72/552>
D	H01L2224/45139	9	Silver (Ag) as principal constituent	<administrative transfer to H10W 72/552>
D	H01L2224/45144	9	Gold (Au) as principal constituent	<administrative transfer to H10W 72/5522>
D	H01L2224/45147	9	Copper (Cu) as principal constituent	<administrative transfer to H10W 72/5525>
D	H01L2224/45149	9	Manganese (Mn) as principal constituent	<administrative transfer to H10W 72/552>

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D	H01L2224/45155	9	Nickel (Ni) as principal constituent	<administrative transfer to H10W 72/552>
D	H01L2224/45157	9	Cobalt (Co) as principal constituent	<administrative transfer to H10W 72/552>
D	H01L2224/4516	9	Iron (Fe) as principal constituent	<administrative transfer to H10W 72/552>
D	H01L2224/45163	8	the principal constituent melting at a temperature of greater than 1550°C	<administrative transfer to H10W 72/552>
D	H01L2224/45164	9	Palladium (Pd) as principal constituent	<administrative transfer to H10W 72/552>
D	H01L2224/45166	9	Titanium (Ti) as principal constituent	<administrative transfer to H10W 72/552>
D	H01L2224/45169	9	Platinum (Pt) as principal constituent	<administrative transfer to H10W 72/552>
D	H01L2224/4517	9	Zirconium (Zr) as principal constituent	<administrative transfer to H10W 72/552>
D	H01L2224/45171	9	Chromium (Cr) as principal constituent	<administrative transfer to H10W 72/552>
D	H01L2224/45172	9	Vanadium (V) as principal constituent	<administrative transfer to H10W 72/552>
D	H01L2224/45173	9	Rhodium (Rh) as principal constituent	<administrative transfer to H10W 72/552>
D	H01L2224/45176	9	Ruthenium (Ru) as principal constituent	<administrative transfer to H10W 72/552>
D	H01L2224/45178	9	Iridium (Ir) as principal constituent	<administrative transfer to H10W 72/552>
D	H01L2224/45179	9	Niobium (Nb) as principal constituent	<administrative transfer to H10W 72/552>
D	H01L2224/4518	9	Molybdenum (Mo) as principal constituent	<administrative transfer to H10W 72/552>
D	H01L2224/45181	9	Tantalum (Ta) as principal constituent	<administrative transfer to H10W 72/552>
D	H01L2224/45183	9	Rhenium (Re) as principal constituent	<administrative transfer to H10W 72/552>
D	H01L2224/45184	9	Tungsten (W) as principal constituent	<administrative transfer to H10W 72/552>
D	H01L2224/45186	7	with a principal constituent of the material being a non metallic, non metalloid inorganic material	<administrative transfer to H10W 72/553>
D	H01L2224/45187	8	Ceramics, e.g. crystalline carbides, nitrides or oxides	<administrative transfer to H10W 72/553>
D	H01L2224/45188	8	Glasses, e.g. amorphous oxides, nitrides or fluorides	<administrative transfer to H10W 72/553>
D	H01L2224/4519	7	with a principal constituent of the material being a polymer, e.g. polyester, phenolic based polymer, epoxy	<administrative transfer to H10W 72/553>
D	H01L2224/45191	8	The principal constituent being an elastomer, e.g. silicones, isoprene, neoprene	<administrative transfer to H10W 72/553>

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D	H01L2224/45193	7	with a principal constituent of the material being a solid not provided for in groups H01L2224/451 - H01L2224/45191, e.g. allotropes of carbon, fullerene, graphite, carbon-nanotubes, diamond	<administrative transfer to H10W 72/553>
D	H01L2224/45194	7	with a principal constituent of the material being a liquid not provided for in groups H01L2224/451 - H01L2224/45191	<administrative transfer to H10W 72/553>
D	H01L2224/45195	7	with a principal constituent of the material being a gas not provided for in groups H01L2224/451 - H01L2224/45191	<administrative transfer to H10W 72/553>
D	H01L2224/45198	7	with a principal constituent of the material being a combination of two or more materials in the form of a matrix with a filler, i.e. being a hybrid material, e.g. segmented structures, foams	<administrative transfer to H10W 72/525 and H10W 72/551 simultaneously>
D	H01L2224/45199	8	Material of the matrix	<administrative transfer to H10W 72/525 and H10W 72/551 simultaneously>
D	H01L2224/452	9	with a principal constituent of the material being a metal or a metalloid, e.g. boron (B), silicon (Si), germanium (Ge), arsenic (As), antimony (Sb), tellurium (Te) and polonium (Po), and alloys thereof	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45201	10	the principal constituent melting at a temperature of less than 400°C	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45205	11	Gallium (Ga) as principal constituent	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45209	11	Indium (In) as principal constituent	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45211	11	Tin (Sn) as principal constituent	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45213	11	Bismuth (Bi) as principal constituent	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45214	11	Thallium (Tl) as principal constituent	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>

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D	H01L2224/45216	11	Lead (Pb) as principal constituent	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45217	10	the principal constituent melting at a temperature of greater than or equal to 400°C and less than 950°C	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45218	11	Zinc (Zn) as principal constituent	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/4522	11	Antimony (Sb) as principal constituent	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45223	11	Magnesium (Mg) as principal constituent	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45224	11	Aluminium (Al) as principal constituent	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45238	10	the principal constituent melting at a temperature of greater than or equal to 950°C and less than 1550°C	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45239	11	Silver (Ag) as principal constituent	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45244	11	Gold (Au) as principal constituent	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45247	11	Copper (Cu) as principal constituent	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45249	11	Manganese (Mn) as principal constituent	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45255	11	Nickel (Ni) as principal constituent	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45257	11	Cobalt (Co) as principal constituent	<administrative transfer to H10W 72/525 and

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				H10W 72/552 simultaneously>
D	H01L2224/4526	11	Iron (Fe) as principal constituent	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45263	10	the principal constituent melting at a temperature of greater than 1550°C	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45264	11	Palladium (Pd) as principal constituent	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45266	11	Titanium (Ti) as principal constituent	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45269	11	Platinum (Pt) as principal constituent	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/4527	11	Zirconium (Zr) as principal constituent	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45271	11	Chromium (Cr) as principal constituent	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45272	11	Vanadium (V) as principal constituent	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45273	11	Rhodium (Rh) as principal constituent	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45276	11	Ruthenium (Ru) as principal constituent	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45278	11	Iridium (Ir) as principal constituent	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45279	11	Niobium (Nb) as principal constituent	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>

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D	H01L2224/4528	11	Molybdenum (Mo) as principal constituent	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45281	11	Tantalum (Ta) as principal constituent	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45283	11	Rhenium (Re) as principal constituent	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45284	11	Tungsten (W) as principal constituent	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45286	9	with a principal constituent of the material being a non metallic, non metalloid inorganic material	<administrative transfer to H10W 72/525 and H10W 72/553 simultaneously>
D	H01L2224/45287	10	Ceramics, e.g. crystalline carbides, nitrides or oxides	<administrative transfer to H10W 72/525 and H10W 72/553 simultaneously>
D	H01L2224/45288	10	Glasses, e.g. amorphous oxides, nitrides or fluorides	<administrative transfer to H10W 72/525 and H10W 72/553 simultaneously>
D	H01L2224/4529	9	with a principal constituent of the material being a polymer, e.g. polyester, phenolic based polymer, epoxy	<administrative transfer to H10W 72/525 and H10W 72/553 simultaneously>
D	H01L2224/45291	10	The principal constituent being an elastomer, e.g. silicones, isoprene, neoprene	<administrative transfer to H10W 72/525 and H10W 72/553 simultaneously>
D	H01L2224/45293	9	with a principal constituent of the material being a solid not provided for in groups H01L2224/452 - H01L2224/45291, e.g. allotropes of carbon, fullerene, graphite, carbon-nanotubes, diamond	<administrative transfer to H10W 72/525 and H10W 72/553 simultaneously>
D	H01L2224/45294	9	with a principal constituent of the material being a liquid not provided for in groups H01L2224/452 - H01L2224/45291	<administrative transfer to H10W 72/525 and H10W 72/553 simultaneously>
D	H01L2224/45295	9	with a principal constituent of the material being a gas not provided for in groups H01L2224/452 - H01L2224/45291	<administrative transfer to H10W 72/525 and H10W 72/553 simultaneously>

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D	H01L2224/45298	8	Fillers	<administrative transfer to H10W 72/525>
D	H01L2224/45299	9	Base material	<administrative transfer to H10W 72/525>
D	H01L2224/453	10	with a principal constituent of the material being a metal or a metalloid, e.g. boron (B), silicon (Si), germanium (Ge), arsenic (As), antimony (Sb), tellurium (Te) and polonium (Po), and alloys thereof	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45301	11	the principal constituent melting at a temperature of less than 400°C	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45305	12	Gallium (Ga) as principal constituent	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45309	12	Indium (In) as principal constituent	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45311	12	Tin (Sn) as principal constituent	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45313	12	Bismuth (Bi) as principal constituent	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45314	12	Thallium (Tl) as principal constituent	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45316	12	Lead (Pb) as principal constituent	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45317	11	the principal constituent melting at a temperature of greater than or equal to 400°C and less than 950°C	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45318	12	Zinc (Zn) as principal constituent	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/4532	12	Antimony (Sb) as principal constituent	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>

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D	H01L2224/45323	12	Magnesium (Mg) as principal constituent	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45324	12	Aluminium (Al) as principal constituent	<administrative transfer to H10W 72/525 and H10W 72/5524 simultaneously>
D	H01L2224/45338	11	the principal constituent melting at a temperature of greater than or equal to 950°C and less than 1550°C	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45339	12	Silver (Ag) as principal constituent	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45344	12	Gold (Au) as principal constituent	<administrative transfer to H10W 72/525 and H10W 72/5522 simultaneously>
D	H01L2224/45347	12	Copper (Cu) as principal constituent	<administrative transfer to H10W 72/525 and H10W 72/5525 simultaneously>
D	H01L2224/45349	12	Manganese (Mn) as principal constituent	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45355	12	Nickel (Ni) as principal constituent	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45357	12	Cobalt (Co) as principal constituent	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/4536	12	Iron (Fe) as principal constituent	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45363	11	the principal constituent melting at a temperature of greater than 1550°C	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45364	12	Palladium (Pd) as principal constituent	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45366	12	Titanium (Ti) as principal constituent	<administrative transfer to H10W 72/525 and

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				H10W 72/552 simultaneously>
D	H01L2224/45369	12	Platinum (Pt) as principal constituent	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/4537	12	Zirconium (Zr) as principal constituent	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45371	12	Chromium (Cr) as principal constituent	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45372	12	Vanadium (V) as principal constituent	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45373	12	Rhodium (Rh) as principal constituent	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45376	12	Ruthenium (Ru) as principal constituent	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45378	12	Iridium (Ir) as principal constituent	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45379	12	Niobium (Nb) as principal constituent	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/4538	12	Molybdenum (Mo) as principal constituent	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45381	12	Tantalum (Ta) as principal constituent	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45383	12	Rhenium (Re) as principal constituent	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45384	12	Tungsten (W) as principal constituent	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>

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D	H01L2224/45386	10	with a principal constituent of the material being a non metallic, non metalloid inorganic material	<administrative transfer to H10W 72/525 and H10W 72/553 simultaneously>
D	H01L2224/45387	11	Ceramics, e.g. crystalline carbides, nitrides or oxides	<administrative transfer to H10W 72/525 and H10W 72/553 simultaneously>
D	H01L2224/45388	11	Glasses, e.g. amorphous oxides, nitrides or fluorides	<administrative transfer to H10W 72/525 and H10W 72/553 simultaneously>
D	H01L2224/4539	10	with a principal constituent of the material being a polymer, e.g. polyester, phenolic based polymer, epoxy	<administrative transfer to H10W 72/525 and H10W 72/553 simultaneously>
D	H01L2224/45391	11	The principal constituent being an elastomer, e.g. silicones, isoprene, neoprene	<administrative transfer to H10W 72/525 and H10W 72/553 simultaneously>
D	H01L2224/45393	10	with a principal constituent of the material being a solid not provided for in groups H01L2224/453 - H01L2224/45391, e.g. allotropes of carbon, fullerene, graphite, carbon-nanotubes, diamond	<administrative transfer to H10W 72/525 and H10W 72/553 simultaneously>
D	H01L2224/45394	10	with a principal constituent of the material being a liquid not provided for in groups H01L2224/453 - H01L2224/45391	<administrative transfer to H10W 72/525 and H10W 72/553 simultaneously>
D	H01L2224/45395	10	with a principal constituent of the material being a gas not provided for in groups H01L2224/453 - H01L2224/45391	<administrative transfer to H10W 72/525 and H10W 72/553 simultaneously>
D	H01L2224/45398	10	with a principal constituent of the material being a combination of two or more materials in the form of a matrix with a filler, i.e. being a hybrid material, e.g. segmented structures, foams	<administrative transfer to H10W 72/525 and H10W 72/553 simultaneously>
D	H01L2224/45399	9	Coating material	<administrative transfer to H10W 72/525 and H10W 72/551 simultaneously>
D	H01L2224/454	10	with a principal constituent of the material being a metal or a metalloid, e.g. boron (B), silicon (Si), germanium (Ge), arsenic (As), antimony (Sb), tellurium (Te) and polonium (Po), and alloys thereof	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45401	11	the principal constituent melting at a temperature of less than 400°C	<administrative transfer to H10W 72/525 and

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				H10W 72/552 simultaneously>
D	H01L2224/45405	12	Gallium (Ga) as principal constituent	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45409	12	Indium (In) as principal constituent	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45411	12	Tin (Sn) as principal constituent	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45413	12	Bismuth (Bi) as principal constituent	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45414	12	Thallium (Tl) as principal constituent	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45416	12	Lead (Pb) as principal constituent	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45417	11	the principal constituent melting at a temperature of greater than or equal to 400°C and less than 950°C	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45418	12	Zinc (Zn) as principal constituent	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/4542	12	Antimony (Sb) as principal constituent	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45423	12	Magnesium (Mg) as principal constituent	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45424	12	Aluminium (Al) as principal constituent	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45438	11	the principal constituent melting at a temperature of greater than or equal to 950°C and less than 1550°C	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>

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D	H01L2224/45439	12	Silver (Ag) as principal constituent	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45444	12	Gold (Au) as principal constituent	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45447	12	Copper (Cu) as principal constituent	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45449	12	Manganese (Mn) as principal constituent	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45455	12	Nickel (Ni) as principal constituent	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45457	12	Cobalt (Co) as principal constituent	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/4546	12	Iron (Fe) as principal constituent	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45463	11	the principal constituent melting at a temperature of greater than 1550°C	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45464	12	Palladium (Pd) as principal constituent	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45466	12	Titanium (Ti) as principal constituent	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45469	12	Platinum (Pt) as principal constituent	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/4547	12	Zirconium (Zr) as principal constituent	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45471	12	Chromium (Cr) as principal constituent	<administrative transfer to H10W 72/525 and

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				H10W 72/552 simultaneously>
D	H01L2224/45472	12	Vanadium (V) as principal constituent	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45473	12	Rhodium (Rh) as principal constituent	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45476	12	Ruthenium (Ru) as principal constituent	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45478	12	Iridium (Ir) as principal constituent	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45479	12	Niobium (Nb) as principal constituent	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/4548	12	Molybdenum (Mo) as principal constituent	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45481	12	Tantalum (Ta) as principal constituent	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45483	12	Rhenium (Re) as principal constituent	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45484	12	Tungsten (W) as principal constituent	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45486	10	with a principal constituent of the material being a non metallic, non metalloid inorganic material	<administrative transfer to H10W 72/525 and H10W 72/553 simultaneously>
D	H01L2224/45487	11	Ceramics, e.g. crystalline carbides, nitrides or oxides	<administrative transfer to H10W 72/525 and H10W 72/553 simultaneously>
D	H01L2224/45488	11	Glasses, e.g. amorphous oxides, nitrides or fluorides	<administrative transfer to H10W 72/525 and H10W 72/553 simultaneously>

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D	H01L2224/4549	10	with a principal constituent of the material being a polymer, e.g. polyester, phenolic based polymer, epoxy	<administrative transfer to H10W 72/525 and H10W 72/553 simultaneously>
D	H01L2224/45491	11	The principal constituent being an elastomer, e.g. silicones, isoprene, neoprene	<administrative transfer to H10W 72/525 and H10W 72/553 simultaneously>
D	H01L2224/45493	10	with a principal constituent of the material being a solid not provided for in groups H01L2224/454 - H01L2224/45491, e.g. allotropes of carbon, fullerene, graphite, carbon-nanotubes, diamond	<administrative transfer to H10W 72/525 and H10W 72/553 simultaneously>
D	H01L2224/45494	10	with a principal constituent of the material being a liquid not provided for in groups H01L2224/454 - H01L2224/45491	<administrative transfer to H10W 72/525 and H10W 72/553 simultaneously>
D	H01L2224/45495	10	with a principal constituent of the material being a gas not provided for in groups H01L2224/454 - H01L2224/45491	<administrative transfer to H10W 72/525 and H10W 72/553 simultaneously>
D	H01L2224/45498	10	with a principal constituent of the material being a combination of two or more materials in the form of a matrix with a filler, i.e. being a hybrid material, e.g. segmented structures, foams	<administrative transfer to H10W 72/525 and H10W 72/553 simultaneously>
D	H01L2224/45499	8	Shape or distribution of the fillers	<administrative transfer to H10W 72/525>
D	H01L2224/4554	5	Coating	<administrative transfer to H10W 72/522>
D	H01L2224/45541	6	Structure	<administrative transfer to H10W 72/523>
D	H01L2224/4555	6	Shape	<administrative transfer to H10W 72/535>
D	H01L2224/4556	6	Disposition, e.g. coating on a part of the core	<administrative transfer to H10W 72/543>
D	H01L2224/45565	6	Single coating layer	<administrative transfer to H10W 72/522>
D	H01L2224/4557	6	Plural coating layers	<administrative transfer to H10W 72/523>
D	H01L2224/45572	7	Two-layer stack coating	<administrative transfer to H10W 72/523>
D	H01L2224/45573	7	Three-layer stack coating	<administrative transfer to H10W 72/523>
D	H01L2224/45574	7	Four-layer stack coating	<administrative transfer to H10W 72/523>
D	H01L2224/45576	7	being mutually engaged together, e.g. through inserts	<administrative transfer to H10W 72/523>

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D	H01L2224/45578	7	being disposed next to each other, e.g. side-to-side arrangements	<administrative transfer to H10W 72/523>
D	H01L2224/45599	6	Material	<administrative transfer to H10W 72/555 and H10W 72/551 simultaneously>
D	H01L2224/456	7	with a principal constituent of the material being a metal or a metalloid, e.g. boron (B), silicon (Si), germanium (Ge), arsenic (As), antimony (Sb), tellurium (Te) and polonium (Po), and alloys thereof	<administrative transfer to H10W 72/555 and H10W 72/552 simultaneously>
D	H01L2224/45601	8	the principal constituent melting at a temperature of less than 400°C	<administrative transfer to H10W 72/555 and H10W 72/552 simultaneously>
D	H01L2224/45605	9	Gallium (Ga) as principal constituent	<administrative transfer to H10W 72/555 and H10W 72/552 simultaneously>
D	H01L2224/45609	9	Indium (In) as principal constituent	<administrative transfer to H10W 72/555 and H10W 72/552 simultaneously>
D	H01L2224/45611	9	Tin (Sn) as principal constituent	<administrative transfer to H10W 72/555 and H10W 72/552 simultaneously>
D	H01L2224/45613	9	Bismuth (Bi) as principal constituent	<administrative transfer to H10W 72/555 and H10W 72/552 simultaneously>
D	H01L2224/45614	9	Thallium (Tl) as principal constituent	<administrative transfer to H10W 72/555 and H10W 72/552 simultaneously>
D	H01L2224/45616	9	Lead (Pb) as principal constituent	<administrative transfer to H10W 72/555 and H10W 72/552 simultaneously>
D	H01L2224/45617	8	the principal constituent melting at a temperature of greater than or equal to 400°C and less than 950°C	<administrative transfer to H10W 72/555 and H10W 72/552 simultaneously>
D	H01L2224/45618	9	Zinc (Zn) as principal constituent	<administrative transfer to H10W 72/555 and H10W 72/552 simultaneously>
D	H01L2224/4562	9	Antimony (Sb) as principal constituent	<administrative transfer to H10W 72/555 and

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				H10W 72/552 simultaneously>
D	H01L2224/45623	9	Magnesium (Mg) as principal constituent	<administrative transfer to H10W 72/555 and H10W 72/552 simultaneously>
D	H01L2224/45624	9	Aluminium (Al) as principal constituent	<administrative transfer to H10W 72/555 and H10W 72/5524 simultaneously>
D	H01L2224/45638	8	the principal constituent melting at a temperature of greater than or equal to 950°C and less than 1550°C	<administrative transfer to H10W 72/555 and H10W 72/552 simultaneously>
D	H01L2224/45639	9	Silver (Ag) as principal constituent	<administrative transfer to H10W 72/555 and H10W 72/552 simultaneously>
D	H01L2224/45644	9	Gold (Au) as principal constituent	<administrative transfer to H10W 72/555 and H10W 72/5522 simultaneously>
D	H01L2224/45647	9	Copper (Cu) as principal constituent	<administrative transfer to H10W 72/555 and H10W 72/5525 simultaneously>
D	H01L2224/45649	9	Manganese (Mn) as principal constituent	<administrative transfer to H10W 72/555 and H10W 72/552 simultaneously>
D	H01L2224/45655	9	Nickel (Ni) as principal constituent	<administrative transfer to H10W 72/555 and H10W 72/552 simultaneously>
D	H01L2224/45657	9	Cobalt (Co) as principal constituent	<administrative transfer to H10W 72/555 and H10W 72/552 simultaneously>
D	H01L2224/4566	9	Iron (Fe) as principal constituent	<administrative transfer to H10W 72/555 and H10W 72/552 simultaneously>
D	H01L2224/45663	8	the principal constituent melting at a temperature of greater than 1550°C	<administrative transfer to H10W 72/555 and H10W 72/552 simultaneously>
D	H01L2224/45664	9	Palladium (Pd) as principal constituent	<administrative transfer to H10W 72/555 and H10W 72/552 simultaneously>

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D	H01L2224/45666	9	Titanium (Ti) as principal constituent	<administrative transfer to H10W 72/555 and H10W 72/552 simultaneously>
D	H01L2224/45669	9	Platinum (Pt) as principal constituent	<administrative transfer to H10W 72/555 and H10W 72/552 simultaneously>
D	H01L2224/4567	9	Zirconium (Zr) as principal constituent	<administrative transfer to H10W 72/555 and H10W 72/552 simultaneously>
D	H01L2224/45671	9	Chromium (Cr) as principal constituent	<administrative transfer to H10W 72/555 and H10W 72/552 simultaneously>
D	H01L2224/45672	9	Vanadium (V) as principal constituent	<administrative transfer to H10W 72/555 and H10W 72/552 simultaneously>
D	H01L2224/45673	9	Rhodium (Rh) as principal constituent	<administrative transfer to H10W 72/555 and H10W 72/552 simultaneously>
D	H01L2224/45676	9	Ruthenium (Ru) as principal constituent	<administrative transfer to H10W 72/555 and H10W 72/552 simultaneously>
D	H01L2224/45678	9	Iridium (Ir) as principal constituent	<administrative transfer to H10W 72/555 and H10W 72/552 simultaneously>
D	H01L2224/45679	9	Niobium (Nb) as principal constituent	<administrative transfer to H10W 72/555 and H10W 72/552 simultaneously>
D	H01L2224/4568	9	Molybdenum (Mo) as principal constituent	<administrative transfer to H10W 72/555 and H10W 72/552 simultaneously>
D	H01L2224/45681	9	Tantalum (Ta) as principal constituent	<administrative transfer to H10W 72/555 and H10W 72/552 simultaneously>
D	H01L2224/45683	9	Rhenium (Re) as principal constituent	<administrative transfer to H10W 72/555 and H10W 72/552 simultaneously>
D	H01L2224/45684	9	Tungsten (W) as principal constituent	<administrative transfer to H10W 72/555 and

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				H10W 72/552 simultaneously>
D	H01L2224/45686	7	with a principal constituent of the material being a non metallic, non metalloid inorganic material	<administrative transfer to H10W 72/555 and H10W 72/553 simultaneously>
D	H01L2224/45687	8	Ceramics, e.g. crystalline carbides, nitrides or oxides	<administrative transfer to H10W 72/555 and H10W 72/553 simultaneously>
D	H01L2224/45688	8	Glasses, e.g. amorphous oxides, nitrides or fluorides	<administrative transfer to H10W 72/555 and H10W 72/553 simultaneously>
D	H01L2224/4569	7	with a principal constituent of the material being a polymer, e.g. polyester, phenolic based polymer, epoxy	<administrative transfer to H10W 72/555 and H10W 72/553 simultaneously>
D	H01L2224/45691	8	The principal constituent being an elastomer, e.g. silicones, isoprene, neoprene	<administrative transfer to H10W 72/555 and H10W 72/553 simultaneously>
D	H01L2224/45693	7	with a principal constituent of the material being a solid not provided for in groups H01L2224/456 - H01L2224/45691, e.g. allotropes of carbon, fullerene, graphite, carbon-nanotubes, diamond	<administrative transfer to H10W 72/555 and H10W 72/553 simultaneously>
D	H01L2224/45694	7	with a principal constituent of the material being a liquid not provided for in groups H01L2224/456 - H01L2224/45691	<administrative transfer to H10W 72/555 and H10W 72/553 simultaneously>
D	H01L2224/45695	7	with a principal constituent of the material being a gas not provided for in groups H01L2224/456 - H01L2224/45691	<administrative transfer to H10W 72/555 and H10W 72/553 simultaneously>
D	H01L2224/45698	7	with a principal constituent of the material being a combination of two or more materials in the form of a matrix with a filler, i.e. being a hybrid material, e.g. segmented structures, foams	<administrative transfer to H10W 72/555 and H10W 72/525 simultaneously>
D	H01L2224/45699	8	Material of the matrix	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/551 simultaneously>
D	H01L2224/457	9	with a principal constituent of the material being a metal or a metalloid, e.g. boron (B), silicon (Si), germanium (Ge), arsenic (As), antimony (Sb), tellurium (Te) and polonium (Po), and alloys thereof	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>

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D	H01L2224/45701	10	the principal constituent melting at a temperature of less than 400°C	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45705	11	Gallium (Ga) as principal constituent	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45709	11	Indium (In) as principal constituent	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45711	11	Tin (Sn) as principal constituent	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45713	11	Bismuth (Bi) as principal constituent	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45714	11	Thallium (Tl) as principal constituent	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45716	11	Lead (Pb) as principal constituent	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45717	10	the principal constituent melting at a temperature of greater than or equal to 400°C and less than 950°C	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45718	11	Zinc (Zn) as principal constituent	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/4572	11	Antimony (Sb) as principal constituent	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45723	11	Magnesium (Mg) as principal constituent	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45724	11	Aluminium (Al) as principal constituent	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/5524 simultaneously>

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D	H01L2224/45738	10	the principal constituent melting at a temperature of greater than or equal to 950°C and less than 1550°C	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45739	11	Silver (Ag) as principal constituent	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45744	11	Gold (Au) as principal constituent	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45747	11	Copper (Cu) as principal constituent	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45749	11	Manganese (Mn) as principal constituent	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45755	11	Nickel (Ni) as principal constituent	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45757	11	Cobalt (Co) as principal constituent	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/4576	11	Iron (Fe) as principal constituent	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45763	10	the principal constituent melting at a temperature of greater than 1550°C	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45764	11	Palladium (Pd) as principal constituent	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45766	11	Titanium (Ti) as principal constituent	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45769	11	Platinum (Pt) as principal constituent	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/4577	11	Zirconium (Zr) as principal constituent	<administrative transfer to H10W 72/555, H10W

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				72/525 and H10W 72/552 simultaneously>
D	H01L2224/45771	11	Chromium (Cr) as principal constituent	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45772	11	Vanadium (V) as principal constituent	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45773	11	Rhodium (Rh) as principal constituent	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45776	11	Ruthenium (Ru) as principal constituent	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45778	11	Iridium (Ir) as principal constituent	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45779	11	Niobium (Nb) as principal constituent	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/4578	11	Molybdenum (Mo) as principal constituent	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45781	11	Tantalum (Ta) as principal constituent	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45783	11	Rhenium (Re) as principal constituent	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45784	11	Tungsten (W) as principal constituent	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45786	9	with a principal constituent of the material being a non metallic, non metalloid inorganic material	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/553 simultaneously>
D	H01L2224/45787	10	Ceramics, e.g. crystalline carbides, nitrides or oxides	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/553 simultaneously>

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D	H01L2224/45788	10	Glasses, e.g. amorphous oxides, nitrides or fluorides	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/553 simultaneously>
D	H01L2224/4579	9	with a principal constituent of the material being a polymer, e.g. polyester, phenolic based polymer, epoxy	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/553 simultaneously>
D	H01L2224/45791	10	The principal constituent being an elastomer, e.g. silicones, isoprene, neoprene	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/553 simultaneously>
D	H01L2224/45793	9	with a principal constituent of the material being a solid not provided for in groups H01L2224/457 - H01L2224/45791, e.g. allotropes of carbon, fullerene, graphite, carbon-nanotubes, diamond	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/553 simultaneously>
D	H01L2224/45794	9	with a principal constituent of the material being a liquid not provided for in groups H01L2224/457 - H01L2224/45791	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/553 simultaneously>
D	H01L2224/45795	9	with a principal constituent of the material being a gas not provided for in groups H01L2224/457 - H01L2224/45791	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/553 simultaneously>
D	H01L2224/45798	8	Fillers	<administrative transfer to H10W 72/555 and H10W 72/525 simultaneously>
D	H01L2224/45799	9	Base material	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/551 simultaneously>
D	H01L2224/458	10	with a principal constituent of the material being a metal or a metalloid, e.g. boron (B), silicon (Si), germanium (Ge), arsenic (As), antimony (Sb), tellurium (Te) and polonium (Po), and alloys thereof	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45801	11	the principal constituent melting at a temperature of less than 400°C	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45805	12	Gallium (Ga) as principal constituent	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45809	12	Indium (In) as principal constituent	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>

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D	H01L2224/45811	12	Tin (Sn) as principal constituent	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45813	12	Bismuth (Bi) as principal constituent	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45814	12	Thallium (Tl) as principal constituent	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45816	12	Lead (Pb) as principal constituent	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45817	11	the principal constituent melting at a temperature of greater than or equal to 400°C and less than 950°C	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45818	12	Zinc (Zn) as principal constituent	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/4582	12	Antimony (Sb) as principal constituent	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45823	12	Magnesium (Mg) as principal constituent	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45824	12	Aluminium (Al) as principal constituent	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45838	11	the principal constituent melting at a temperature of greater than or equal to 950°C and less than 1550°C	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45839	12	Silver (Ag) as principal constituent	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45844	12	Gold (Au) as principal constituent	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45847	12	Copper (Cu) as principal constituent	<administrative transfer to H10W 72/555, H10W

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				72/525 and H10W 72/552 simultaneously>
D	H01L2224/45849	12	Manganese (Mn) as principal constituent	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45855	12	Nickel (Ni) as principal constituent	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45857	12	Cobalt (Co) as principal constituent	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/4586	12	Iron (Fe) as principal constituent	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45863	11	the principal constituent melting at a temperature of greater than 1550°C	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45864	12	Palladium (Pd) as principal constituent	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45866	12	Titanium (Ti) as principal constituent	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45869	12	Platinum (Pt) as principal constituent	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/4587	12	Zirconium (Zr) as principal constituent	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45871	12	Chromium (Cr) as principal constituent	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45872	12	Vanadium (V) as principal constituent	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45873	12	Rhodium (Rh) as principal constituent	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>

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D	H01L2224/45876	12	Ruthenium (Ru) as principal constituent	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45878	12	Iridium (Ir) as principal constituent	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45879	12	Niobium (Nb) as principal constituent	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/4588	12	Molybdenum (Mo) as principal constituent	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45881	12	Tantalum (Ta) as principal constituent	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45883	12	Rhenium (Re) as principal constituent	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45884	12	Tungsten (W) as principal constituent	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45886	10	with a principal constituent of the material being a non metallic, non metalloid inorganic material	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/553 simultaneously>
D	H01L2224/45887	11	Ceramics, e.g. crystalline carbides, nitrides or oxides	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/553 simultaneously>
D	H01L2224/45888	11	Glasses, e.g. amorphous oxides, nitrides or fluorides	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/553 simultaneously>
D	H01L2224/4589	10	with a principal constituent of the material being a polymer, e.g. polyester, phenolic based polymer, epoxy	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/553 simultaneously>
D	H01L2224/45891	11	The principal constituent being an elastomer, e.g. silicones, isoprene, neoprene	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/553 simultaneously>
D	H01L2224/45893	10	with a principal constituent of the material being a solid not provided for in groups	<administrative transfer to H10W 72/555, H10W

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			H01L2224/458 - H01L2224/45891, e.g. allotropes of carbon, fullerene, graphite, carbon-nanotubes, diamond	72/525 and H10W 72/553 simultaneously>
D	H01L2224/45894	10	with a principal constituent of the material being a liquid not provided for in groups H01L2224/458 - H01L2224/45891	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/553 simultaneously>
D	H01L2224/45895	10	with a principal constituent of the material being a gas not provided for in groups H01L2224/458 - H01L2224/45891	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/553 simultaneously>
D	H01L2224/45898	10	with a principal constituent of the material being a combination of two or more materials in the form of a matrix with a filler, i.e. being a hybrid material, e.g. segmented structures, foams	<administrative transfer to H10W 72/555 and H10W 72/525 simultaneously>
D	H01L2224/45899	9	Coating material	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/551 simultaneously>
D	H01L2224/459	10	with a principal constituent of the material being a metal or a metalloid, e.g. boron (B), silicon (Si), germanium (Ge), arsenic (As), antimony (Sb), tellurium (Te) and polonium (Po), and alloys thereof	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45901	11	the principal constituent melting at a temperature of less than 400°C	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45905	12	Gallium (Ga) as principal constituent	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45909	12	Indium (In) as principal constituent	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45911	12	Tin (Sn) as principal constituent	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45913	12	Bismuth (Bi) as principal constituent	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45914	12	Thallium (Tl) as principal constituent	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>

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D	H01L2224/45916	12	Lead (Pb) as principal constituent	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45917	11	the principal constituent melting at a temperature of greater than or equal to 400°C and less than 950°C	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45918	12	Zinc (Zn) as principal constituent	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/4592	12	Antimony (Sb) as principal constituent	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45923	12	Magnesium (Mg) as principal constituent	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45924	12	Aluminium (Al) as principal constituent	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45938	11	the principal constituent melting at a temperature of greater than or equal to 950°C and less than 1550°C	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45939	12	Silver (Ag) as principal constituent	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45944	12	Gold (Au) as principal constituent	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45947	12	Copper (Cu) as principal constituent	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45949	12	Manganese (Mn) as principal constituent	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45955	12	Nickel (Ni) as principal constituent	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45957	12	Cobalt (Co) as principal constituent	<administrative transfer to H10W 72/555, H10W

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				72/525 and H10W 72/552 simultaneously>
D	H01L2224/4596	12	Iron (Fe) as principal constituent	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45963	11	the principal constituent melting at a temperature of greater than 1550°C	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45964	12	Palladium (Pd) as principal constituent	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45966	12	Titanium (Ti) as principal constituent	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45969	12	Platinum (Pt) as principal constituent	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/4597	12	Zirconium (Zr) as principal constituent	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45971	12	Chromium (Cr) as principal constituent	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45972	12	Vanadium (V) as principal constituent	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45973	12	Rhodium (Rh) as principal constituent	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45976	12	Ruthenium (Ru) as principal constituent	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45978	12	Iridium (Ir) as principal constituent	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45979	12	Niobium (Nb) as principal constituent	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>

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D	H01L2224/4598	12	Molybdenum (Mo) as principal constituent	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45981	12	Tantalum (Ta) as principal constituent	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45983	12	Rhenium (Re) as principal constituent	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45984	12	Tungsten (W) as principal constituent	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L2224/45986	10	with a principal constituent of the material being a non metallic, non metalloid inorganic material	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/553 simultaneously>
D	H01L2224/45987	11	Ceramics, e.g. crystalline carbides, nitrides or oxides	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/553 simultaneously>
D	H01L2224/45988	11	Glasses, e.g. amorphous oxides, nitrides or fluorides	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/553 simultaneously>
D	H01L2224/4599	10	with a principal constituent of the material being a polymer, e.g. polyester, phenolic based polymer, epoxy	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/553 simultaneously>
D	H01L2224/45991	11	The principal constituent being an elastomer, e.g. silicones, isoprene, neoprene	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/553 simultaneously>
D	H01L2224/45993	10	with a principal constituent of the material being a solid not provided for in groups H01L2224/459 - H01L2224/45991, e.g. allotropes of carbon, fullerene, graphite, carbon-nanotubes, diamond	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/553 simultaneously>
D	H01L2224/45994	10	with a principal constituent of the material being a liquid not provided for in groups H01L2224/459 - H01L2224/45991	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/553 simultaneously>
D	H01L2224/45995	10	with a principal constituent of the material being a gas not provided for in groups H01L2224/459 - H01L2224/45991	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/553 simultaneously>

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D	H01L2224/45998	10	with a principal constituent of the material being a combination of two or more materials in the form of a matrix with a filler, i.e. being a hybrid material, e.g. segmented structures, foams	<administrative transfer to H10W 72/555 and H10W 72/525 simultaneously>
D	H01L2224/45999	8	Shape or distribution of the fillers	<administrative transfer to H10W 72/555 and H10W 72/525 simultaneously>
D	H01L2224/46	4	of a plurality of wire connectors	<administrative transfer to H10W 72/50>
D	H01L2224/47	3	Structure, shape, material or disposition of the wire connectors after the connecting process	<administrative transfer to H10W 72/07551 and H10W 72/50 simultaneously>
D	H01L2224/48	4	of an individual wire connector	<administrative transfer to H10W 72/07551 and H10W 72/50 simultaneously>
D	H01L2224/4801	5	Structure	<administrative transfer to H10W 72/07552 and H10W 72/521 simultaneously>
D	H01L2224/48011	6	Length	<administrative transfer to H10W 72/07552 and H10W 72/521 simultaneously>
D	H01L2224/4805	5	Shape	<administrative transfer to H10W 72/07553 and H10W 72/531 simultaneously>
D	H01L2224/4807	6	of bonding interfaces, e.g. interlocking features	<administrative transfer to H10W 72/07553 and H10W 72/531 simultaneously>
D	H01L2224/4809	6	Loop shape	<administrative transfer to H10W 72/07553 and H10W 72/531 simultaneously>
D	H01L2224/48091	7	Arched	<no transfer>
D	H01L2224/48092	7	Helix	<administrative transfer to H10W 72/5368>
D	H01L2224/48095	7	Kinked	<administrative transfer to H10W 72/5366>
D	H01L2224/48096	8	the kinked part being in proximity to the bonding area on the semiconductor or solid-state body	<administrative transfer to H10W 72/5366>

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D	H01L2224/48097	8	the kinked part being in proximity to the bonding area outside the semiconductor or solid-state body	<administrative transfer to H10W 72/5366>
D	H01L2224/481	5	Disposition	<administrative transfer to H10W 72/07554>
D	H01L2224/48101	6	Connecting bonding areas at the same height, e.g. horizontal bond	<administrative transfer to H10W 72/07554>
D	H01L2224/48105	6	Connecting bonding areas at different heights	<administrative transfer to H10W 72/07554>
D	H01L2224/48106	7	the connector being orthogonal to a side surface of the semiconductor or solid-state body, e.g. parallel layout	<administrative transfer to H10W 72/5445>
D	H01L2224/48108	7	the connector not being orthogonal to a side surface of the semiconductor or solid-state body, e.g. fanned-out connectors, radial layout	<administrative transfer to H10W 72/5449>
D	H01L2224/4811	6	Connecting to a bonding area of the semiconductor or solid-state body located at the far end of the body with respect to the bonding area outside the semiconductor or solid-state body	<administrative transfer to H10W 72/07554>
D	H01L2224/48111	6	the wire connector extending above another semiconductor or solid-state body	<administrative transfer to H10W 72/07554>
D	H01L2224/4813	6	Connecting within a semiconductor or solid-state body, i.e. fly wire, bridge wire	<administrative transfer to H10W 72/5453>
D	H01L2224/48132	7	with an intermediate bond, e.g. continuous wire daisy chain	<administrative transfer to H10W 72/5453>
D	H01L2224/48135	6	Connecting between different semiconductor or solid-state bodies, i.e. chip-to-chip	<administrative transfer to H10W 90/751>
D	H01L2224/48137	7	the bodies being arranged next to each other, e.g. on a common substrate	<administrative transfer to H10W 90/753>
D	H01L2224/48138	8	the wire connector connecting to a bonding area disposed in a recess of the surface	<administrative transfer to H10W 90/753>
D	H01L2224/48139	8	with an intermediate bond, e.g. continuous wire daisy chain	<administrative transfer to H10W 90/753>
D	H01L2224/4814	8	the wire connector connecting to a bonding area protruding from the surface	<administrative transfer to H10W 90/753>
D	H01L2224/48141	7	the bodies being arranged on opposite sides of a substrate, e.g. mirror arrangements	<administrative transfer to H10W 90/751>
D	H01L2224/48145	7	the bodies being stacked	<administrative transfer to H10W 90/752>
D	H01L2224/48147	8	with an intermediate bond, e.g. continuous wire daisy chain	<administrative transfer to H10W 90/752>
D	H01L2224/48148	8	the wire connector connecting to a bonding area disposed in a recess of the surface	<administrative transfer to H10W 90/752>
D	H01L2224/48149	8	the wire connector connecting to a bonding area protruding from the surface	<administrative transfer to H10W 90/752>

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D	H01L2224/48151	6	Connecting between a semiconductor or solid-state body and an item not being a semiconductor or solid-state body, e.g. chip-to-substrate, chip-to-passive	<administrative transfer to H10W 90/751>
D	H01L2224/48153	7	the body and the item being arranged next to each other, e.g. on a common substrate	<administrative transfer to H10W 90/751>
D	H01L2224/48155	8	the item being non-metallic, e.g. insulating substrate with or without metallisation	<administrative transfer to H10W 90/755>
D	H01L2224/48157	9	connecting the wire to a bond pad of the item	<administrative transfer to H10W 90/755>
D	H01L2224/48158	10	the bond pad being disposed in a recess of the surface of the item	<administrative transfer to H10W 90/755>
D	H01L2224/48159	10	the bond pad protruding from the surface of the item	<administrative transfer to H10W 90/755>
D	H01L2224/4816	9	connecting the wire to a pin of the item	<administrative transfer to H10W 90/755>
D	H01L2224/48163	9	connecting the wire to a potential ring of the item	<administrative transfer to H10W 90/755>
D	H01L2224/48165	9	connecting the wire to a via metallisation of the item	<administrative transfer to H10W 90/755>
D	H01L2224/48175	8	the item being metallic	<administrative transfer to H10W 90/755>
D	H01L2224/48177	9	connecting the wire to a bond pad of the item	<administrative transfer to H10W 90/755>
D	H01L2224/48178	9	the bond pad being disposed in a recess of the surface of the item	<administrative transfer to H10W 90/755>
D	H01L2224/48179	9	the bond pad protruding from the surface of the item	<administrative transfer to H10W 90/755>
D	H01L2224/48183	9	connecting the wire to a potential ring of the item	<administrative transfer to H10W 90/755>
D	H01L2224/48195	8	the item being a discrete passive component	<administrative transfer to H10W 90/759>
D	H01L2224/48221	7	the body and the item being stacked	<administrative transfer to H10W 90/751>
D	H01L2224/48225	8	the item being non-metallic, e.g. insulating substrate with or without metallisation	<administrative transfer to H10W 90/754>
D	H01L2224/48227	9	connecting the wire to a bond pad of the item	<administrative transfer to H10W 90/754>
D	H01L2224/48228	10	the bond pad being disposed in a recess of the surface of the item	<administrative transfer to H10W 90/754>
D	H01L2224/48229	10	the bond pad protruding from the surface of the item	<administrative transfer to H10W 90/754>
D	H01L2224/4823	9	connecting the wire to a pin of the item	<administrative transfer to H10W 90/754>
D	H01L2224/48233	9	connecting the wire to a potential ring of the item	<administrative transfer to H10W 90/754>
D	H01L2224/48235	9	connecting the wire to a via metallisation of the item	<administrative transfer to H10W 90/754>

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D	H01L2224/48237	9	connecting the wire to a die pad of the item	<administrative transfer to H10W 90/754>
D	H01L2224/4824	9	Connecting between the body and an opposite side of the item with respect to the body	<administrative transfer to H10W 90/754>
D	H01L2224/48245	8	the item being metallic	<administrative transfer to H10W 90/756>
D	H01L2224/48247	9	connecting the wire to a bond pad of the item	<administrative transfer to H10W 90/756>
D	H01L2224/48248	10	the bond pad being disposed in a recess of the surface of the item	<administrative transfer to H10W 90/756>
D	H01L2224/48249	10	the bond pad protruding from the surface of the item	<administrative transfer to H10W 90/756>
D	H01L2224/48253	9	connecting the wire to a potential ring of the item	<administrative transfer to H10W 90/756>
D	H01L2224/48257	9	connecting the wire to a die pad of the item	<administrative transfer to H10W 90/756>
D	H01L2224/4826	9	Connecting between the body and an opposite side of the item with respect to the body	<administrative transfer to H10W 90/756>
D	H01L2224/48265	8	the item being a discrete passive component	<administrative transfer to H10W 90/758>
D	H01L2224/484	5	Connecting portions	<administrative transfer to H10W 72/50>
D	H01L2224/4845	6	Details of ball bonds	<administrative transfer to H10W 72/536>
D	H01L2224/48451	7	Shape	<administrative transfer to H10W 72/536>
D	H01L2224/48453	8	of the interface with the bonding area	<administrative transfer to H10W 72/536>
D	H01L2224/48455	6	Details of wedge bonds	<administrative transfer to H10W 72/5363>
D	H01L2224/48456	7	Shape	<administrative transfer to H10W 72/5363>
D	H01L2224/48458	8	of the interface with the bonding area	<administrative transfer to H10W 72/5363>
D	H01L2224/4846	6	with multiple bonds on the same bonding area	<administrative transfer to H10W 72/5438>
D	H01L2224/48463	6	the connecting portion on the bonding area of the semiconductor or solid-state body being a ball bond	<administrative transfer to H10W 72/536>
D	H01L2224/48464	7	the other connecting portion not on the bonding area also being a ball bond, i.e. ball-to-ball	<administrative transfer to H10W 72/536>
D	H01L2224/48465	7	the other connecting portion not on the bonding area being a wedge bond, i.e. ball-to-wedge, regular stitch	<administrative transfer to H10W 72/536 and H10W 72/5363 simultaneously>

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D	H01L2224/4847	6	the connecting portion on the bonding area of the semiconductor or solid-state body being a wedge bond	<administrative transfer to H10W 72/5363>
D	H01L2224/48471	7	the other connecting portion not on the bonding area being a ball bond, i.e. wedge-to-ball, reverse stitch	<administrative transfer to H10W 72/536 and H10W 72/5363 simultaneously>
D	H01L2224/48472	7	the other connecting portion not on the bonding area also being a wedge bond, i.e. wedge-to-wedge	<administrative transfer to H10W 72/5363>
D	H01L2224/48475	6	connected to auxiliary connecting means on the bonding areas, e.g. pre-ball, wedge-on-ball, ball-on-ball	<administrative transfer to H10W 72/5434>
D	H01L2224/48476	7	between the wire connector and the bonding area	<administrative transfer to H10W 72/5434>
D	H01L2224/48477	8	being a pre-ball (i.e. a ball formed by capillary bonding)	<administrative transfer to H10W 72/5434>
D	H01L2224/48478	9	the connecting portion being a wedge bond, i.e. wedge on pre-ball	<administrative transfer to H10W 72/5434>
D	H01L2224/48479	10	on the semiconductor or solid-state body	<administrative transfer to H10W 72/5434>
D	H01L2224/4848	10	outside the semiconductor or solid-state body	<administrative transfer to H10W 72/5434>
D	H01L2224/48481	9	the connecting portion being a ball bond, i.e. ball on pre-ball	<administrative transfer to H10W 72/5434>
D	H01L2224/48482	10	on the semiconductor or solid-state body	<administrative transfer to H10W 72/5434>
D	H01L2224/48483	10	outside the semiconductor or solid-state body	<administrative transfer to H10W 72/5434>
D	H01L2224/48484	9	being a plurality of pre-balls disposed side-to-side	<administrative transfer to H10W 72/5434>
D	H01L2224/48485	10	the connecting portion being a wedge bond, i.e. wedge on pre-ball	<administrative transfer to H10W 72/5434>
D	H01L2224/48486	11	on the semiconductor or solid-state body	<administrative transfer to H10W 72/5434>
D	H01L2224/48487	11	outside the semiconductor or solid-state body	<administrative transfer to H10W 72/5434>
D	H01L2224/48488	10	the connecting portion being a ball bond, i.e. ball on pre-ball	<administrative transfer to H10W 72/5434>
D	H01L2224/48489	11	on the semiconductor or solid-state body	<administrative transfer to H10W 72/5434>
D	H01L2224/4849	11	outside the semiconductor or solid-state body	<administrative transfer to H10W 72/5434>
D	H01L2224/48491	8	being an additional member attached to the bonding area through an adhesive or solder, e.g. buffer pad	<administrative transfer to H10W 72/5434>
D	H01L2224/48496	7	not being interposed between the wire connector and the bonding area	<administrative transfer to H10W 72/5434>

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D	H01L2224/48499	7	Material of the auxiliary connecting means	<administrative transfer to H10W 72/5434>
D	H01L2224/485	5	Material	<administrative transfer to H10W 72/07555 and H10W 72/551 simultaneously>
D	H01L2224/48505	6	at the bonding interface	<administrative transfer to H10W 72/07555 and H10W 72/551 simultaneously>
D	H01L2224/48506	7	comprising an eutectic alloy	<administrative transfer to H10W 72/07555 and H10W 72/5527 simultaneously>
D	H01L2224/48507	7	comprising an intermetallic compound	<administrative transfer to H10W 72/07555 and H10W 72/5528 simultaneously>
D	H01L2224/4851	7	Morphology of the connecting portion, e.g. grain size distribution	<administrative transfer to H10W 72/07555 and H10W 72/551 simultaneously>
D	H01L2224/48511	8	Heat affected zone [HAZ]	<administrative transfer to H10W 72/07555 and H10W 72/551 simultaneously>
D	H01L2224/4852	7	Bonding interface between the connecting portion and the bonding area	<administrative transfer to H10W 72/07555 and H10W 72/551 simultaneously>
D	H01L2224/48599	7	Principal constituent of the connecting portion of the wire connector being Gold (Au)	<administrative transfer to H10W 72/59 and H10W 72/5522 simultaneously>
D	H01L2224/486	8	with a principal constituent of the bonding area being a metal or a metalloid, e.g. boron (B), silicon (Si), germanium (Ge), arsenic (As), antimony (Sb), tellurium (Te) and polonium (Po), and alloys thereof	<administrative transfer to H10W 72/59, H10W 72/5522 and H10W 72/952 simultaneously>
D	H01L2224/48601	9	the principal constituent melting at a temperature of less than 400°C	<administrative transfer to H10W 72/59, H10W 72/5522 and H10W 72/952 simultaneously>
D	H01L2224/48605	10	Gallium (Ga) as principal constituent	<administrative transfer to H10W 72/59, H10W 72/5522 and H10W 72/952 simultaneously>
D	H01L2224/48609	10	Indium (In) as principal constituent	<administrative transfer to H10W 72/59, H10W

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				72/5522 and H10W 72/952 simultaneously>
D	H01L2224/48611	10	Tin (Sn) as principal constituent	<administrative transfer to H10W 72/59, H10W 72/5522 and H10W 72/952 simultaneously>
D	H01L2224/48613	10	Bismuth (Bi) as principal constituent	<administrative transfer to H10W 72/59, H10W 72/5522 and H10W 72/952 simultaneously>
D	H01L2224/48614	10	Thallium (Tl) as principal constituent	<administrative transfer to H10W 72/59, H10W 72/5522 and H10W 72/952 simultaneously>
D	H01L2224/48616	10	Lead (Pb) as principal constituent	<administrative transfer to H10W 72/59, H10W 72/5522 and H10W 72/952 simultaneously>
D	H01L2224/48617	9	the principal constituent melting at a temperature of greater than or equal to 400°C and less than 950 °C	<administrative transfer to H10W 72/59, H10W 72/5522 and H10W 72/952 simultaneously>
D	H01L2224/48618	10	Zinc (Zn) as principal constituent	<administrative transfer to H10W 72/59, H10W 72/5522 and H10W 72/952 simultaneously>
D	H01L2224/4862	10	Antimony (Sb) as principal constituent	<administrative transfer to H10W 72/59, H10W 72/5522 and H10W 72/952 simultaneously>
D	H01L2224/48623	10	Magnesium (Mg) as principal constituent	<administrative transfer to H10W 72/59, H10W 72/5522 and H10W 72/952 simultaneously>
D	H01L2224/48624	10	Aluminium (Al) as principal constituent	<administrative transfer to H10W 72/59, H10W 72/5522 and H10W 72/952 simultaneously>
D	H01L2224/48638	9	the principal constituent melting at a temperature of greater than or equal to 950°C and less than 1550°C	<administrative transfer to H10W 72/59, H10W 72/5522 and H10W 72/952 simultaneously>
D	H01L2224/48639	10	Silver (Ag) as principal constituent	<administrative transfer to H10W 72/59, H10W 72/5522 and H10W 72/952 simultaneously>
D	H01L2224/48644	10	Gold (Au) as principal constituent	<administrative transfer to H10W 72/59, H10W 72/5522 and H10W 72/952 simultaneously>

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D	H01L2224/48647	10	Copper (Cu) as principal constituent	<administrative transfer to H10W 72/59, H10W 72/5522 and H10W 72/952 simultaneously>
D	H01L2224/48649	10	Manganese (Mn) as principal constituent	<administrative transfer to H10W 72/59, H10W 72/5522 and H10W 72/952 simultaneously>
D	H01L2224/48655	10	Nickel (Ni) as principal constituent	<administrative transfer to H10W 72/59, H10W 72/5522 and H10W 72/952 simultaneously>
D	H01L2224/48657	10	Cobalt (Co) as principal constituent	<administrative transfer to H10W 72/59, H10W 72/5522 and H10W 72/952 simultaneously>
D	H01L2224/4866	10	Iron (Fe) as principal constituent	<administrative transfer to H10W 72/59, H10W 72/5522 and H10W 72/952 simultaneously>
D	H01L2224/48663	9	the principal constituent melting at a temperature of greater than 1550°C	<administrative transfer to H10W 72/59, H10W 72/5522 and H10W 72/952 simultaneously>
D	H01L2224/48664	10	Palladium (Pd) as principal constituent	<administrative transfer to H10W 72/59, H10W 72/5522 and H10W 72/952 simultaneously>
D	H01L2224/48666	10	Titanium (Ti) as principal constituent	<administrative transfer to H10W 72/59, H10W 72/5522 and H10W 72/952 simultaneously>
D	H01L2224/48669	10	Platinum (Pt) as principal constituent	<administrative transfer to H10W 72/59, H10W 72/5522 and H10W 72/952 simultaneously>
D	H01L2224/4867	10	Zirconium (Zr) as principal constituent	<administrative transfer to H10W 72/59, H10W 72/5522 and H10W 72/952 simultaneously>
D	H01L2224/48671	10	Chromium (Cr) as principal constituent	<administrative transfer to H10W 72/59, H10W 72/5522 and H10W 72/952 simultaneously>
D	H01L2224/48672	10	Vanadium (V) as principal constituent	<administrative transfer to H10W 72/59, H10W 72/5522 and H10W 72/952 simultaneously>
D	H01L2224/48673	10	Rhodium (Rh) as principal constituent	<administrative transfer to H10W 72/59, H10W

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				72/5522 and H10W 72/952 simultaneously>
D	H01L2224/48678	10	Iridium (Ir) as principal constituent	<administrative transfer to H10W 72/59, H10W 72/5522 and H10W 72/952 simultaneously>
D	H01L2224/48679	10	Niobium (Nb) as principal constituent	<administrative transfer to H10W 72/59, H10W 72/5522 and H10W 72/952 simultaneously>
D	H01L2224/4868	10	Molybdenum (Mo) as principal constituent	<administrative transfer to H10W 72/59, H10W 72/5522 and H10W 72/952 simultaneously>
D	H01L2224/48681	10	Tantalum (Ta) as principal constituent	<administrative transfer to H10W 72/59, H10W 72/5522 and H10W 72/952 simultaneously>
D	H01L2224/48683	10	Rhenium (Re) as principal constituent	<administrative transfer to H10W 72/59, H10W 72/5522 and H10W 72/952 simultaneously>
D	H01L2224/48684	10	Tungsten (W) as principal constituent	<administrative transfer to H10W 72/59, H10W 72/5522 and H10W 72/952 simultaneously>
D	H01L2224/48686	8	with a principal constituent of the bonding area being a non metallic, non metalloid inorganic material	<administrative transfer to H10W 72/59, H10W 72/5522 and H10W 72/953 simultaneously>
D	H01L2224/48687	9	Ceramics, e.g. crystalline carbides, nitrides or oxides	<administrative transfer to H10W 72/59, H10W 72/5522 and H10W 72/953 simultaneously>
D	H01L2224/48688	9	Glasses, e.g. amorphous oxides, nitrides or fluorides	<administrative transfer to H10W 72/59, H10W 72/5522 and H10W 72/953 simultaneously>
D	H01L2224/4869	8	with a principal constituent of the bonding area being a polymer, e.g. polyester, phenolic based polymer, epoxy	<administrative transfer to H10W 72/59, H10W 72/5522 and H10W 72/953 simultaneously>
D	H01L2224/48691	9	The principal constituent being an elastomer, e.g. silicones, isoprene, neoprene	<administrative transfer to H10W 72/59, H10W 72/5522 and H10W 72/953 simultaneously>
D	H01L2224/48693	8	with a principal constituent of the bonding area being a solid not provided for in groups H01L2224/486 - H01L2224/4869, e.g.	<administrative transfer to H10W 72/59, H10W 72/5522 and H10W 72/953 simultaneously>

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			allotropes of carbon, fullerene, graphite, carbon-nanotubes, diamond	
D	H01L2224/48694	8	with a principal constituent of the bonding area being a liquid not provided for in groups H01L2224/486 - H01L2224/4869	<administrative transfer to H10W 72/59, H10W 72/5522 and H10W 72/953 simultaneously>
D	H01L2224/48698	8	with a principal constituent of the bonding area being a combination of two or more material regions, i.e. being a hybrid material, e.g. segmented structures, island patterns	<administrative transfer to H10W 72/59, H10W 72/5522 and H10W 72/953 simultaneously>
D	H01L2224/48699	7	Principal constituent of the connecting portion of the wire connector being Aluminium (Al)	<administrative transfer to H10W 72/59 and H10W 72/5524 simultaneously>
D	H01L2224/487	8	with a principal constituent of the bonding area being a metal or a metalloid, e.g. boron (B), silicon (Si), germanium (Ge), arsenic (As), antimony (Sb), tellurium (Te) and polonium (Po), and alloys thereof	<administrative transfer to H10W 72/59, H10W 72/5524 and H10W 72/952 simultaneously>
D	H01L2224/48701	9	the principal constituent melting at a temperature of less than 400°C	<administrative transfer to H10W 72/59, H10W 72/5524 and H10W 72/952 simultaneously>
D	H01L2224/48705	10	Gallium (Ga) as principal constituent	<administrative transfer to H10W 72/59, H10W 72/5524 and H10W 72/952 simultaneously>
D	H01L2224/48709	10	Indium (In) as principal constituent	<administrative transfer to H10W 72/59, H10W 72/5524 and H10W 72/952 simultaneously>
D	H01L2224/48711	10	Tin (Sn) as principal constituent	<administrative transfer to H10W 72/59, H10W 72/5524 and H10W 72/952 simultaneously>
D	H01L2224/48713	10	Bismuth (Bi) as principal constituent	<administrative transfer to H10W 72/59, H10W 72/5524 and H10W 72/952 simultaneously>
D	H01L2224/48714	10	Thallium (Tl) as principal constituent	<administrative transfer to H10W 72/59, H10W 72/5524 and H10W 72/952 simultaneously>
D	H01L2224/48716	10	Lead (Pb) as principal constituent	<administrative transfer to H10W 72/59, H10W 72/5524 and H10W 72/952 simultaneously>
D	H01L2224/48717	9	the principal constituent melting at a temperature of greater than or equal to 400°C and less than 950 °C	<administrative transfer to H10W 72/59, H10W 72/952 simultaneously>

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				72/5524 and H10W 72/952 simultaneously>
D	H01L2224/48718	10	Zinc (Zn) as principal constituent	<administrative transfer to H10W 72/59, H10W 72/5524 and H10W 72/952 simultaneously>
D	H01L2224/4872	10	Antimony (Sb) as principal constituent	<administrative transfer to H10W 72/59, H10W 72/5524 and H10W 72/952 simultaneously>
D	H01L2224/48723	10	Magnesium (Mg) as principal constituent	<administrative transfer to H10W 72/59, H10W 72/5524 and H10W 72/952 simultaneously>
D	H01L2224/48724	10	Aluminium (Al) as principal constituent	<administrative transfer to H10W 72/59, H10W 72/5524 and H10W 72/952 simultaneously>
D	H01L2224/48738	9	the principal constituent melting at a temperature of greater than or equal to 950°C and less than 1550°C	<administrative transfer to H10W 72/59, H10W 72/5524 and H10W 72/952 simultaneously>
D	H01L2224/48739	10	Silver (Ag) as principal constituent	<administrative transfer to H10W 72/59, H10W 72/5524 and H10W 72/952 simultaneously>
D	H01L2224/48744	10	Gold (Au) as principal constituent	<administrative transfer to H10W 72/59, H10W 72/5524 and H10W 72/952 simultaneously>
D	H01L2224/48747	10	Copper (Cu) as principal constituent	<administrative transfer to H10W 72/59, H10W 72/5524 and H10W 72/952 simultaneously>
D	H01L2224/48749	10	Manganese (Mn) as principal constituent	<administrative transfer to H10W 72/59, H10W 72/5524 and H10W 72/952 simultaneously>
D	H01L2224/48755	10	Nickel (Ni) as principal constituent	<administrative transfer to H10W 72/59, H10W 72/5524 and H10W 72/952 simultaneously>
D	H01L2224/48757	10	Cobalt (Co) as principal constituent	<administrative transfer to H10W 72/59, H10W 72/5524 and H10W 72/952 simultaneously>
D	H01L2224/4876	10	Iron (Fe) as principal constituent	<administrative transfer to H10W 72/59, H10W 72/5524 and H10W 72/952 simultaneously>

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D	H01L2224/48763	9	the principal constituent melting at a temperature of greater than 1550°C	<administrative transfer to H10W 72/59, H10W 72/5524 and H10W 72/952 simultaneously>
D	H01L2224/48764	10	Palladium (Pd) as principal constituent	<administrative transfer to H10W 72/59, H10W 72/5524 and H10W 72/952 simultaneously>
D	H01L2224/48766	10	Titanium (Ti) as principal constituent	<administrative transfer to H10W 72/59, H10W 72/5524 and H10W 72/952 simultaneously>
D	H01L2224/48769	10	Platinum (Pt) as principal constituent	<administrative transfer to H10W 72/59, H10W 72/5524 and H10W 72/952 simultaneously>
D	H01L2224/4877	10	Zirconium (Zr) as principal constituent	<administrative transfer to H10W 72/59, H10W 72/5524 and H10W 72/952 simultaneously>
D	H01L2224/48771	10	Chromium (Cr) as principal constituent	<administrative transfer to H10W 72/59, H10W 72/5524 and H10W 72/952 simultaneously>
D	H01L2224/48772	10	Vanadium (V) as principal constituent	<administrative transfer to H10W 72/59, H10W 72/5524 and H10W 72/952 simultaneously>
D	H01L2224/48773	10	Rhodium (Rh) as principal constituent	<administrative transfer to H10W 72/59, H10W 72/5524 and H10W 72/952 simultaneously>
D	H01L2224/48778	10	Iridium (Ir) as principal constituent	<administrative transfer to H10W 72/59, H10W 72/5524 and H10W 72/952 simultaneously>
D	H01L2224/48779	10	Niobium (Nb) as principal constituent	<administrative transfer to H10W 72/59, H10W 72/5524 and H10W 72/952 simultaneously>
D	H01L2224/4878	10	Molybdenum (Mo) as principal constituent	<administrative transfer to H10W 72/59, H10W 72/5524 and H10W 72/952 simultaneously>
D	H01L2224/48781	10	Tantalum (Ta) as principal constituent	<administrative transfer to H10W 72/59, H10W 72/5524 and H10W 72/952 simultaneously>
D	H01L2224/48783	10	Rhenium (Re) as principal constituent	<administrative transfer to H10W 72/59, H10W

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				72/5524 and H10W 72/952 simultaneously>
D	H01L2224/48784	10	Tungsten (W) as principal constituent	<administrative transfer to H10W 72/59, H10W 72/5524 and H10W 72/952 simultaneously>
D	H01L2224/48786	8	with a principal constituent of the bonding area being a non metallic, non metalloid inorganic material	<administrative transfer to H10W 72/59, H10W 72/5524 and H10W 72/953 simultaneously>
D	H01L2224/48787	9	Ceramics, e.g. crystalline carbides, nitrides or oxides	<administrative transfer to H10W 72/59, H10W 72/5524 and H10W 72/953 simultaneously>
D	H01L2224/48788	9	Glasses, e.g. amorphous oxides, nitrides or fluorides	<administrative transfer to H10W 72/59, H10W 72/5524 and H10W 72/953 simultaneously>
D	H01L2224/4879	8	with a principal constituent of the bonding area being a polymer, e.g. polyester, phenolic based polymer, epoxy	<administrative transfer to H10W 72/59, H10W 72/5524 and H10W 72/953 simultaneously>
D	H01L2224/48791	9	The principal constituent being an elastomer, e.g. silicones, isoprene, neoprene	<administrative transfer to H10W 72/59, H10W 72/5524 and H10W 72/953 simultaneously>
D	H01L2224/48793	8	with a principal constituent of the bonding area being a solid not provided for in groups H01L2224/487 - H01L2224/4879, e.g. allotropes of carbon, fullerene, graphite, carbon-nanotubes, diamond	<administrative transfer to H10W 72/59, H10W 72/5524 and H10W 72/953 simultaneously>
D	H01L2224/48794	8	with a principal constituent of the bonding area being a liquid not provided for in groups H01L2224/487 - H01L2224/4879	<administrative transfer to H10W 72/59, H10W 72/5524 and H10W 72/953 simultaneously>
D	H01L2224/48798	8	with a principal constituent of the bonding area being a combination of two or more material regions, i.e. being a hybrid material, e.g. segmented structures, island patterns	<administrative transfer to H10W 72/59, H10W 72/5524 and H10W 72/953 simultaneously>
D	H01L2224/48799	7	Principal constituent of the connecting portion of the wire connector being Copper (Cu)	<administrative transfer to H10W 72/59 and H10W 72/5525 simultaneously>
D	H01L2224/488	8	with a principal constituent of the bonding area being a metal or a metalloid, e.g. boron (B), silicon (Si), germanium (Ge), arsenic (As), antimony (Sb), tellurium (Te) and polonium (Po), and alloys thereof	<administrative transfer to H10W 72/59, H10W 72/5525 and H10W 72/952 simultaneously>
D	H01L2224/48801	9	the principal constituent melting at a temperature of less than 400°C	<administrative transfer to H10W 72/59, H10W

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				72/5525 and H10W 72/952 simultaneously>
D	H01L2224/48805	10	Gallium (Ga) as principal constituent	<administrative transfer to H10W 72/59, H10W 72/5525 and H10W 72/952 simultaneously>
D	H01L2224/48809	10	Indium (In) as principal constituent	<administrative transfer to H10W 72/59, H10W 72/5525 and H10W 72/952 simultaneously>
D	H01L2224/48811	10	Tin (Sn) as principal constituent	<administrative transfer to H10W 72/59, H10W 72/5525 and H10W 72/952 simultaneously>
D	H01L2224/48813	10	Bismuth (Bi) as principal constituent	<administrative transfer to H10W 72/59, H10W 72/5525 and H10W 72/952 simultaneously>
D	H01L2224/48814	10	Thallium (Tl) as principal constituent	<administrative transfer to H10W 72/59, H10W 72/5525 and H10W 72/952 simultaneously>
D	H01L2224/48816	10	Lead (Pb) as principal constituent	<administrative transfer to H10W 72/59, H10W 72/5525 and H10W 72/952 simultaneously>
D	H01L2224/48817	9	the principal constituent melting at a temperature of greater than or equal to 400°C and less than 950 °C	<administrative transfer to H10W 72/59, H10W 72/5525 and H10W 72/952 simultaneously>
D	H01L2224/48818	10	Zinc (Zn) as principal constituent	<administrative transfer to H10W 72/59, H10W 72/5525 and H10W 72/952 simultaneously>
D	H01L2224/4882	10	Antimony (Sb) as principal constituent	<administrative transfer to H10W 72/59, H10W 72/5525 and H10W 72/952 simultaneously>
D	H01L2224/48823	10	Magnesium (Mg) as principal constituent	<administrative transfer to H10W 72/59, H10W 72/5525 and H10W 72/952 simultaneously>
D	H01L2224/48824	10	Aluminium (Al) as principal constituent	<administrative transfer to H10W 72/59, H10W 72/5525 and H10W 72/952 simultaneously>
D	H01L2224/48838	9	the principal constituent melting at a temperature of greater than or equal to 950°C and less than 1550°C	<administrative transfer to H10W 72/59, H10W 72/5525 and H10W 72/952 simultaneously>

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D	H01L2224/48839	10	Silver (Ag) as principal constituent	<administrative transfer to H10W 72/59, H10W 72/5525 and H10W 72/952 simultaneously>
D	H01L2224/48844	10	Gold (Au) as principal constituent	<administrative transfer to H10W 72/59, H10W 72/5525 and H10W 72/952 simultaneously>
D	H01L2224/48847	10	Copper (Cu) as principal constituent	<administrative transfer to H10W 72/59, H10W 72/5525 and H10W 72/952 simultaneously>
D	H01L2224/48849	10	Manganese (Mn) as principal constituent	<administrative transfer to H10W 72/59, H10W 72/5525 and H10W 72/952 simultaneously>
D	H01L2224/48855	10	Nickel (Ni) as principal constituent	<administrative transfer to H10W 72/59, H10W 72/5525 and H10W 72/952 simultaneously>
D	H01L2224/48857	10	Cobalt (Co) as principal constituent	<administrative transfer to H10W 72/59, H10W 72/5525 and H10W 72/952 simultaneously>
D	H01L2224/4886	10	Iron (Fe) as principal constituent	<administrative transfer to H10W 72/59, H10W 72/5525 and H10W 72/952 simultaneously>
D	H01L2224/48863	9	the principal constituent melting at a temperature of greater than 1550°C	<administrative transfer to H10W 72/59, H10W 72/5525 and H10W 72/952 simultaneously>
D	H01L2224/48864	10	Palladium (Pd) as principal constituent	<administrative transfer to H10W 72/59, H10W 72/5525 and H10W 72/952 simultaneously>
D	H01L2224/48866	10	Titanium (Ti) as principal constituent	<administrative transfer to H10W 72/59, H10W 72/5525 and H10W 72/952 simultaneously>
D	H01L2224/48869	10	Platinum (Pt) as principal constituent	<administrative transfer to H10W 72/59, H10W 72/5525 and H10W 72/952 simultaneously>
D	H01L2224/4887	10	Zirconium (Zr) as principal constituent	<administrative transfer to H10W 72/59, H10W 72/5525 and H10W 72/952 simultaneously>
D	H01L2224/48871	10	Chromium (Cr) as principal constituent	<administrative transfer to H10W 72/59, H10W

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				72/5525 and H10W 72/952 simultaneously>
D	H01L2224/48872	10	Vanadium (V) as principal constituent	<administrative transfer to H10W 72/59, H10W 72/5525 and H10W 72/952 simultaneously>
D	H01L2224/48873	10	Rhodium (Rh) as principal constituent	<administrative transfer to H10W 72/59, H10W 72/5525 and H10W 72/952 simultaneously>
D	H01L2224/48878	10	Iridium (Ir) as principal constituent	<administrative transfer to H10W 72/59, H10W 72/5525 and H10W 72/952 simultaneously>
D	H01L2224/48879	10	Niobium (Nb) as principal constituent	<administrative transfer to H10W 72/59, H10W 72/5525 and H10W 72/952 simultaneously>
D	H01L2224/4888	10	Molybdenum (Mo) as principal constituent	<administrative transfer to H10W 72/59, H10W 72/5525 and H10W 72/952 simultaneously>
D	H01L2224/48881	10	Tantalum (Ta) as principal constituent	<administrative transfer to H10W 72/59, H10W 72/5525 and H10W 72/952 simultaneously>
D	H01L2224/48883	10	Rhenium (Re) as principal constituent	<administrative transfer to H10W 72/59, H10W 72/5525 and H10W 72/952 simultaneously>
D	H01L2224/48884	10	Tungsten (W) as principal constituent	<administrative transfer to H10W 72/59, H10W 72/5525 and H10W 72/952 simultaneously>
D	H01L2224/48886	8	with a principal constituent of the bonding area being a non metallic, non metalloid inorganic material	<administrative transfer to H10W 72/59, H10W 72/5525 and H10W 72/953 simultaneously>
D	H01L2224/48887	9	Ceramics, e.g. crystalline carbides, nitrides or oxides	<administrative transfer to H10W 72/59, H10W 72/5525 and H10W 72/953 simultaneously>
D	H01L2224/48888	9	Glasses, e.g. amorphous oxides, nitrides or fluorides	<administrative transfer to H10W 72/59, H10W 72/5525 and H10W 72/953 simultaneously>
D	H01L2224/4889	8	with a principal constituent of the bonding area being a polymer, e.g. polyester, phenolic based polymer, epoxy	<administrative transfer to H10W 72/59, H10W 72/5525 and H10W 72/953 simultaneously>

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D	H01L2224/48891	9	The principal constituent being an elastomer, e.g. silicones, isoprene, neoprene	<administrative transfer to H10W 72/59, H10W 72/5525 and H10W 72/953 simultaneously>
D	H01L2224/48893	8	with a principal constituent of the bonding area being a solid not provided for in groups H01L2224/488 - H01L2224/4889, e.g. allotropes of carbon, fullerene, graphite, carbon-nanotubes, diamond	<administrative transfer to H10W 72/59, H10W 72/5525 and H10W 72/953 simultaneously>
D	H01L2224/48894	8	with a principal constituent of the bonding area being a liquid not provided for in groups H01L2224/488 - H01L2224/4889	<administrative transfer to H10W 72/59, H10W 72/5525 and H10W 72/953 simultaneously>
D	H01L2224/48898	8	with a principal constituent of the bonding area being a combination of two or more material regions, i.e. being a hybrid material, e.g. segmented structures, island patterns	<administrative transfer to H10W 72/59, H10W 72/5525 and H10W 72/953 simultaneously>
D	H01L2224/4899	5	Auxiliary members for wire connectors, e.g. flow-barriers, reinforcing structures, spacers, alignment aids	<administrative transfer to H10W 72/581>
D	H01L2224/48991	6	being formed on the semiconductor or solid-state body to be connected	<administrative transfer to H10W 72/581>
D	H01L2224/48992	7	Reinforcing structures	<administrative transfer to H10W 72/07553>
D	H01L2224/48993	7	Alignment aids	<administrative transfer to H10W 72/585>
D	H01L2224/48996	6	being formed on an item to be connected not being a semiconductor or solid-state body	<administrative transfer to H10W 72/581>
D	H01L2224/48997	7	Reinforcing structures	<administrative transfer to H10W 72/583>
D	H01L2224/48998	7	Alignment aids	<administrative transfer to H10W 72/585>
D	H01L2224/49	4	of a plurality of wire connectors	<administrative transfer to H10W 72/50>
D	H01L2224/4901	5	Structure	<administrative transfer to H10W 72/07552 and H10W 72/528 simultaneously>
D	H01L2224/4903	6	Connectors having different sizes, e.g. different diameters	<administrative transfer to H10W 72/07552 and H10W 72/527 simultaneously>
D	H01L2224/4905	5	Shape	<administrative transfer to H10W 72/07552 and H10W 72/537 simultaneously>
D	H01L2224/49051	6	Connectors having different shapes	<administrative transfer to H10W 72/07553 and H10W 72/537 simultaneously>

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D	H01L2224/49052	7	Different loop heights	<administrative transfer to H10W 72/07553 and H10W 72/537 simultaneously>
D	H01L2224/4909	6	Loop shape arrangement	<administrative transfer to H10W 72/07553 and H10W 72/537 simultaneously>
D	H01L2224/49095	7	parallel in plane	<administrative transfer to H10W 72/07553 and H10W 72/537 simultaneously>
D	H01L2224/49096	8	horizontal	<administrative transfer to H10W 72/07553 and H10W 72/537 simultaneously>
D	H01L2224/49097	8	vertical	<administrative transfer to H10W 72/07553 and H10W 72/537 simultaneously>
D	H01L2224/491	5	Disposition	<administrative transfer to H10W 72/07554 and H10W 72/547 simultaneously>
D	H01L2224/49105	6	Connecting at different heights	<administrative transfer to H10W 72/07554 and H10W 72/547 simultaneously>
D	H01L2224/49107	7	on the semiconductor or solid-state body	<administrative transfer to H10W 72/07554 and H10W 72/547 simultaneously>
D	H01L2224/49109	7	outside the semiconductor or solid-state body	<administrative transfer to H10W 72/07554 and H10W 72/547 simultaneously>
D	H01L2224/4911	6	the connectors being bonded to at least one common bonding area, e.g. daisy chain	<administrative transfer to H10W 72/5473>
D	H01L2224/49111	7	the connectors connecting two common bonding areas, e.g. Litz or braid wires	<administrative transfer to H10W 72/5475>
D	H01L2224/49112	7	the connectors connecting a common bonding area on the semiconductor or solid-state body to different bonding areas outside the body, e.g. diverging wires	<administrative transfer to H10W 72/5473>
D	H01L2224/49113	7	the connectors connecting different bonding areas on the semiconductor or solid-state body to a common bonding area outside the body, e.g. converging wires	<administrative transfer to H10W 72/5473>
D	H01L2224/4912	6	Layout	<administrative transfer to H10W 72/07554>

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D	H01L2224/4917	7	Crossed wires	<administrative transfer to H10W 72/07554>
D	H01L2224/49171	7	Fan-out arrangements	<administrative transfer to H10W 72/5449>
D	H01L2224/49173	8	Radial fan-out arrangements	<administrative transfer to H10W 72/5449>
D	H01L2224/49174	7	Stacked arrangements	<administrative transfer to H10W 72/07554>
D	H01L2224/49175	7	Parallel arrangements	<administrative transfer to H10W 72/5445>
D	H01L2224/49176	8	Wire connectors having the same loop shape and height	<administrative transfer to H10W 72/5445>
D	H01L2224/49177	7	Combinations of different arrangements	<administrative transfer to H10W 72/07554>
D	H01L2224/49179	8	Corner adaptations, i.e. disposition of the wire connectors at the corners of the semiconductor or solid-state body	<administrative transfer to H10W 72/07554>
D	H01L2224/4918	6	being disposed on at least two different sides of the body, e.g. dual array	<administrative transfer to H10W 72/07554>
D	H01L2224/494	5	Connecting portions	<administrative transfer to H10W 72/50>
D	H01L2224/4941	6	the connecting portions being stacked	<administrative transfer to H10W 72/547 and H10W 72/5434 simultaneously>
D	H01L2224/4942	7	Ball bonds	<administrative transfer to H10W 72/547, H10W 72/5434 and H10W 72/536 simultaneously>
D	H01L2224/49421	8	on the semiconductor or solid-state body	<administrative transfer to H10W 72/547, H10W 72/5434 and H10W 72/536 simultaneously>
D	H01L2224/49422	8	outside the semiconductor or solid-state body	<administrative transfer to H10W 72/547, H10W 72/5434 and H10W 72/536 simultaneously>
D	H01L2224/49425	7	Wedge bonds	<administrative transfer to H10W 72/547, H10W 72/5434 and H10W 72/536 simultaneously>
D	H01L2224/49426	8	on the semiconductor or solid-state body	<administrative transfer to H10W 72/547, H10W 72/5434 and H10W 72/536 simultaneously>
D	H01L2224/49427	8	outside the semiconductor or solid-state body	<administrative transfer to H10W 72/547, H10W 72/5434 and H10W 72/536 simultaneously>

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D	H01L2224/49429	7	Wedge and ball bonds	<administrative transfer to H10W 72/547, H10W 72/5434, H10W 72/536 and H10W 72/5363 simultaneously>
D	H01L2224/4943	6	the connecting portions being staggered	<administrative transfer to H10W 72/547 and H10W 72/07554 simultaneously>
D	H01L2224/49431	7	on the semiconductor or solid-state body	<administrative transfer to H10W 72/547 and H10W 72/07554 simultaneously>
D	H01L2224/49433	7	outside the semiconductor or solid-state body	<administrative transfer to H10W 72/547 and H10W 72/07554 simultaneously>
D	H01L2224/4945	6	Wire connectors having connecting portions of different types on the semiconductor or solid-state body, e.g. regular and reverse stitches	<administrative transfer to H10W 72/537 and H10W 72/07553 simultaneously>
D	H01L2224/495	5	Material	<administrative transfer to H10W 72/07555 and H10W 72/551 simultaneously>
D	H01L2224/49505	6	Connectors having different materials	<administrative transfer to H10W 72/07555 and H10W 72/557 simultaneously>
D	H01L2224/50	2	Tape automated bonding [TAB] connectors, i.e. film carriers; Manufacturing methods related thereto	<administrative transfer to H10W 72/701>
D	H01L2224/63	2	Connectors not provided for in any of the groups H01L 2224/10 - H01L 2224/50 and subgroups; Manufacturing methods related thereto	<administrative transfer to H10W 72/00>
D	H01L2224/64	3	Manufacturing methods	<administrative transfer to H10W 72/00>
D	H01L2224/65	3	Structure, shape, material or disposition of the connectors prior to the connecting process	<administrative transfer to H10W 72/00>
D	H01L2224/66	4	of an individual connector	<administrative transfer to H10W 72/00>
D	H01L2224/67	4	of a plurality of connectors	<administrative transfer to H10W 72/00>
D	H01L2224/68	3	Structure, shape, material or disposition of the connectors after the connecting process	<administrative transfer to H10W 72/00>
D	H01L2224/69	4	of an individual connector	<administrative transfer to H10W 72/00>
D	H01L2224/70	4	of a plurality of connectors	<administrative transfer to H10W 72/00>

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D	H01L2224/71	1	Means for bonding not being attached to, or not being formed on, the surface to be connected	<administrative transfer to H10W 72/00>
D	H01L2224/72	2	Detachable connecting means consisting of mechanical auxiliary parts connecting the device, e.g. pressure contacts using springs or clips	<administrative transfer to H10W 72/00>
D	H01L2224/73	1	Means for bonding being of different types provided for in two or more of groups H01L2224/10, H01L2224/18, H01L2224/26, H01L2224/34, H01L2224/42, H01L2224/50, H01L2224/63, H01L2224/71	<administrative transfer to H10W 72/851>
D	H01L2224/731	2	Location prior to the connecting process	<administrative transfer to H10W 72/851>
D	H01L2224/73101	3	on the same surface	<administrative transfer to H10W 72/853>
D	H01L2224/73103	4	Bump and layer connectors	<administrative transfer to H10W 72/856>
D	H01L2224/73104	5	the bump connector being embedded into the layer connector	<administrative transfer to H10W 74/15>
D	H01L2224/73151	3	on different surfaces	<administrative transfer to H10W 72/874>
D	H01L2224/73153	4	Bump and layer connectors	<administrative transfer to H10W 72/856>
D	H01L2224/732	2	Location after the connecting process	<administrative transfer to H10W 72/851>
D	H01L2224/73201	3	on the same surface	<administrative transfer to H10W 72/853>
D	H01L2224/73203	4	Bump and layer connectors	<administrative transfer to H10W 72/856>
D	H01L2224/73204	5	the bump connector being embedded into the layer connector	<administrative transfer to H10W 74/15>
D	H01L2224/73205	4	Bump and strap connectors	<administrative transfer to H10W 72/862>
D	H01L2224/73207	4	Bump and wire connectors	<administrative transfer to H10W 72/859>
D	H01L2224/73209	4	Bump and HDI connectors	<administrative transfer to H10W 72/853>
D	H01L2224/73211	4	Bump and TAB connectors	<administrative transfer to H10W 72/853>
D	H01L2224/73213	4	Layer and strap connectors	<administrative transfer to H10W 72/868>
D	H01L2224/73215	4	Layer and wire connectors	<administrative transfer to H10W 72/865>
D	H01L2224/73217	4	Layer and HDI connectors	<administrative transfer to H10W 72/853>
D	H01L2224/73219	4	Layer and TAB connectors	<administrative transfer to H10W 72/853>

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D	H01L2224/73221	4	Strap and wire connectors	<administrative transfer to H10W 72/871>
D	H01L2224/73223	4	Strap and HDI connectors	<administrative transfer to H10W 72/853>
D	H01L2224/73225	4	Strap and TAB connectors	<administrative transfer to H10W 72/853>
D	H01L2224/73227	4	Wire and HDI connectors	<administrative transfer to H10W 72/853>
D	H01L2224/73229	4	Wire and TAB connectors	<administrative transfer to H10W 72/853>
D	H01L2224/73231	4	HDI and TAB connectors	<administrative transfer to H10W 72/853>
D	H01L2224/73251	3	on different surfaces	<administrative transfer to H10W 72/874>
D	H01L2224/73253	4	Bump and layer connectors	<administrative transfer to H10W 72/877>
D	H01L2224/73255	4	Bump and strap connectors	<administrative transfer to H10W 72/881>
D	H01L2224/73257	4	Bump and wire connectors	<administrative transfer to H10W 72/879>
D	H01L2224/73259	4	Bump and HDI connectors	<administrative transfer to H10W 72/874>
D	H01L2224/73261	4	Bump and TAB connectors	<administrative transfer to H10W 72/874>
D	H01L2224/73263	4	Layer and strap connectors	<administrative transfer to H10W 72/886>
D	H01L2224/73265	4	Layer and wire connectors	<administrative transfer to H10W 72/884>
D	H01L2224/73267	4	Layer and HDI connectors	<administrative transfer to H10W 72/874>
D	H01L2224/73269	4	Layer and TAB connectors	<administrative transfer to H10W 72/874>
D	H01L2224/73271	4	Strap and wire connectors	<administrative transfer to H10W 72/889>
D	H01L2224/73273	4	Strap and HDI connectors	<administrative transfer to H10W 72/874>
D	H01L2224/73275	4	Strap and TAB connectors	<administrative transfer to H10W 72/874>
D	H01L2224/73277	4	Wire and HDI connectors	<administrative transfer to H10W 72/874>
D	H01L2224/73279	4	Wire and TAB connectors	<administrative transfer to H10W 72/874>
D	H01L2224/73281	4	HDI and TAB connectors	<administrative transfer to H10W 72/874>
D	H01L2224/74	1	Apparatus for manufacturing arrangements for connecting or disconnecting semiconductor or solid-state bodies and for methods related thereto	<administrative transfer to H10W 72/071>

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D	H01L2224/741	2	Apparatus for manufacturing means for bonding, e.g. connectors	<administrative transfer to H10W 72/011>
D	H01L2224/742	3	Apparatus for manufacturing bump connectors	<administrative transfer to H10W 72/0112>
D	H01L2224/743	3	Apparatus for manufacturing layer connectors	<administrative transfer to H10W 72/0113>
D	H01L2224/744	3	Apparatus for manufacturing strap connectors	<administrative transfer to H10W 72/0115>
D	H01L2224/745	3	Apparatus for manufacturing wire connectors	<administrative transfer to H10W 72/0116>
D	H01L2224/749	3	Tools for reworking, e.g. for shaping	<administrative transfer to H10W 72/011>
D	H01L2224/75	2	Apparatus for connecting with bump connectors or layer connectors	<administrative transfer to H10W 72/0711>
D	H01L2224/75001	3	Calibration means	<administrative transfer to H10W 72/07113>
D	H01L2224/7501	3	Means for cleaning, e.g. brushes, for hydro blasting, for ultrasonic cleaning, for dry ice blasting, using gas-flow, by etching, by applying flux or plasma	<administrative transfer to H10W 72/07118>
D	H01L2224/751	3	Means for controlling the bonding environment, e.g. valves, vacuum pumps	<administrative transfer to H10W 72/07125>
D	H01L2224/75101	4	Chamber	<administrative transfer to H10W 72/07125>
D	H01L2224/75102	5	Vacuum chamber	<administrative transfer to H10W 72/07125>
D	H01L2224/7511	5	High pressure chamber	<administrative transfer to H10W 72/07125>
D	H01L2224/7515	3	Means for applying permanent coating, e.g. in-situ coating	<administrative transfer to H10W 72/07131>
D	H01L2224/75151	4	Means for direct writing	<administrative transfer to H10W 72/07131>
D	H01L2224/75152	5	Syringe	<administrative transfer to H10W 72/07131>
D	H01L2224/75153	6	integrated into the bonding head	<administrative transfer to H10W 72/07131>
D	H01L2224/75155	5	Jetting means, e.g. ink jet	<administrative transfer to H10W 72/07131>
D	H01L2224/75158	5	including a laser	<administrative transfer to H10W 72/07131>
D	H01L2224/75161	4	Means for screen printing, e.g. roller, squeegee, screen stencil	<administrative transfer to H10W 72/07131>
D	H01L2224/7517	4	Means for applying a preform, e.g. laminator	<administrative transfer to H10W 72/07131>
D	H01L2224/75171	5	including a vacuum-bag	<administrative transfer to H10W 72/07131>
D	H01L2224/7518	4	Means for blanket deposition	<administrative transfer to H10W 72/07131>

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D	H01L2224/75181	5	for spin coating, i.e. spin coater	<administrative transfer to H10W 72/07131>
D	H01L2224/75182	5	for curtain coating	<administrative transfer to H10W 72/07131>
D	H01L2224/75183	5	for immersion coating, i.e. bath	<administrative transfer to H10W 72/07131>
D	H01L2224/75184	5	for spray coating, i.e. nozzle	<administrative transfer to H10W 72/07131>
D	H01L2224/75185	5	Means for physical vapour deposition [PVD], e.g. evaporation, sputtering	<administrative transfer to H10W 72/07131>
D	H01L2224/75186	5	Means for sputtering, e.g. target	<administrative transfer to H10W 72/07131>
D	H01L2224/75187	5	Means for evaporation	<administrative transfer to H10W 72/07131>
D	H01L2224/75188	5	Means for chemical vapour deposition [CVD], e.g. for laser CVD	<administrative transfer to H10W 72/07131>
D	H01L2224/75189	5	Means for plating, e.g. for electroplating, electroless plating	<administrative transfer to H10W 72/07131>
D	H01L2224/752	3	Protection means against electrical discharge	<administrative transfer to H10W 72/07139>
D	H01L2224/7525	3	Means for applying energy, e.g. heating means	<administrative transfer to H10W 72/07141>
D	H01L2224/75251	4	in the lower part of the bonding apparatus, e.g. in the apparatus chuck	<administrative transfer to H10W 72/07141>
D	H01L2224/75252	4	in the upper part of the bonding apparatus, e.g. in the bonding head	<administrative transfer to H10W 72/07141>
D	H01L2224/75253	4	adapted for localised heating	<administrative transfer to H10W 72/07141>
D	H01L2224/7526	4	Polychromatic heating lamp	<administrative transfer to H10W 72/07141>
D	H01L2224/75261	4	Laser	<administrative transfer to H10W 72/07141>
D	H01L2224/75262	5	in the lower part of the bonding apparatus, e.g. in the apparatus chuck	<administrative transfer to H10W 72/07141>
D	H01L2224/75263	5	in the upper part of the bonding apparatus, e.g. in the bonding head	<administrative transfer to H10W 72/07141>
D	H01L2224/75264	4	by induction heating, i.e. coils	<administrative transfer to H10W 72/07141>
D	H01L2224/75265	5	in the lower part of the bonding apparatus, e.g. in the apparatus chuck	<administrative transfer to H10W 72/07141>
D	H01L2224/75266	5	in the upper part of the bonding apparatus, e.g. in the bonding head	<administrative transfer to H10W 72/07141>
D	H01L2224/75267	4	Flame torch, e.g. hydrogen torch	<administrative transfer to H10W 72/07141>
D	H01L2224/75268	4	Discharge electrode	<administrative transfer to H10W 72/07141>
D	H01L2224/75269	5	Shape of the discharge electrode	<administrative transfer to H10W 72/07141>

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D	H01L2224/7527	5	Material of the discharge electrode	<administrative transfer to H10W 72/07141>
D	H01L2224/75271	5	Circuitry of the discharge electrode	<administrative transfer to H10W 72/07141>
D	H01L2224/75272	4	Oven	<administrative transfer to H10W 72/07141>
D	H01L2224/7528	4	Resistance welding electrodes, i.e. for ohmic heating	<administrative transfer to H10W 72/07141>
D	H01L2224/75281	5	in the lower part of the bonding apparatus, e.g. in the apparatus chuck	<administrative transfer to H10W 72/07141>
D	H01L2224/75282	5	in the upper part of the bonding apparatus, e.g. in the bonding head	<administrative transfer to H10W 72/07141>
D	H01L2224/75283	4	by infrared heating, e.g. infrared heating lamp	<administrative transfer to H10W 72/07141>
D	H01L2224/753	4	by means of pressure	<administrative transfer to H10W 72/07141>
D	H01L2224/75301	5	Bonding head	<administrative transfer to H10W 72/07141>
D	H01L2224/75302	6	Shape	<administrative transfer to H10W 72/07141>
D	H01L2224/75303	7	of the pressing surface	<administrative transfer to H10W 72/07141>
D	H01L2224/75304	8	being curved	<administrative transfer to H10W 72/07141>
D	H01L2224/75305	8	comprising protrusions	<administrative transfer to H10W 72/07141>
D	H01L2224/7531	7	of other parts	<administrative transfer to H10W 72/07141>
D	H01L2224/75312	6	Material	<administrative transfer to H10W 72/07141>
D	H01L2224/75313	6	Removable bonding head	<administrative transfer to H10W 72/07141>
D	H01L2224/75314	6	Auxiliary members on the pressing surface	<administrative transfer to H10W 72/07141>
D	H01L2224/75315	7	Elastomer inlay	<administrative transfer to H10W 72/07141>
D	H01L2224/75316	8	with retaining mechanisms	<administrative transfer to H10W 72/07141>
D	H01L2224/75317	7	Removable auxiliary member	<administrative transfer to H10W 72/07141>
D	H01L2224/75318	7	Shape of the auxiliary member	<administrative transfer to H10W 72/07141>
D	H01L2224/7532	7	Material of the auxiliary member	<administrative transfer to H10W 72/07141>
D	H01L2224/75343	5	by ultrasonic vibrations	<administrative transfer to H10W 72/07141>
D	H01L2224/75344	6	Eccentric cams	<administrative transfer to H10W 72/07141>

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D	H01L2224/75345	7	in the lower part of the bonding apparatus, e.g. in the apparatus chuck	<administrative transfer to H10W 72/07141>
D	H01L2224/75346	7	in the upper part of the bonding apparatus, e.g. in the bonding head	<administrative transfer to H10W 72/07141>
D	H01L2224/75347	6	Piezoelectric transducers	<administrative transfer to H10W 72/07141>
D	H01L2224/75348	7	in the lower part of the bonding apparatus, e.g. in the apparatus chuck	<administrative transfer to H10W 72/07141>
D	H01L2224/75349	7	in the upper part of the bonding apparatus, e.g. in the bonding head	<administrative transfer to H10W 72/07141>
D	H01L2224/7535	6	Stable and mobile yokes	<administrative transfer to H10W 72/07141>
D	H01L2224/75351	7	in the lower part of the bonding apparatus, e.g. in the apparatus chuck	<administrative transfer to H10W 72/07141>
D	H01L2224/75352	7	in the upper part of the bonding apparatus, e.g. in the bonding head	<administrative transfer to H10W 72/07141>
D	H01L2224/75353	6	Ultrasonic horns	<administrative transfer to H10W 72/07141>
D	H01L2224/75354	7	in the lower part of the bonding apparatus, e.g. in the apparatus chuck	<administrative transfer to H10W 72/07141>
D	H01L2224/75355	7	Design, e.g. of the wave guide	<administrative transfer to H10W 72/07141>
D	H01L2224/755	3	Cooling means	<administrative transfer to H10W 72/07152>
D	H01L2224/75501	4	in the lower part of the bonding apparatus, e.g. in the apparatus chuck	<administrative transfer to H10W 72/07152>
D	H01L2224/75502	4	in the upper part of the bonding apparatus, e.g. in the bonding head	<administrative transfer to H10W 72/07152>
D	H01L2224/7555	3	Mechanical means, e.g. for planarising, pressing, stamping	<administrative transfer to H10W 72/07163>
D	H01L2224/756	3	Means for supplying the connector to be connected in the bonding apparatus	<administrative transfer to H10W 72/07168>
D	H01L2224/75601	4	Storing means	<administrative transfer to H10W 72/07168>
D	H01L2224/75611	4	Feeding means	<administrative transfer to H10W 72/07168>
D	H01L2224/75621	4	Holding means	<administrative transfer to H10W 72/07168>
D	H01L2224/7565	3	Means for transporting the components to be connected	<administrative transfer to H10W 72/07173>
D	H01L2224/75651	4	Belt conveyor	<administrative transfer to H10W 72/07173>
D	H01L2224/75652	4	Chain conveyor	<administrative transfer to H10W 72/07173>
D	H01L2224/75653	4	Vibrating conveyor	<administrative transfer to H10W 72/07173>
D	H01L2224/75654	4	Pneumatic conveyor	<administrative transfer to H10W 72/07173>

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D	H01L2224/75655	4	in a fluid	<administrative transfer to H10W 72/07173>
D	H01L2224/757	3	Means for aligning	<administrative transfer to H10W 72/07178>
D	H01L2224/75701	4	in the lower part of the bonding apparatus, e.g. in the apparatus chuck	<administrative transfer to H10W 72/07178>
D	H01L2224/75702	4	in the upper part of the bonding apparatus, e.g. in the bonding head	<administrative transfer to H10W 72/07178>
D	H01L2224/75703	4	Mechanical holding means	<administrative transfer to H10W 72/07178>
D	H01L2224/75704	5	in the lower part of the bonding apparatus, e.g. in the apparatus chuck	<administrative transfer to H10W 72/07178>
D	H01L2224/75705	5	in the upper part of the bonding apparatus, e.g. in the bonding head	<administrative transfer to H10W 72/07178>
D	H01L2224/75723	4	Electrostatic holding means	<administrative transfer to H10W 72/07178>
D	H01L2224/75724	5	in the lower part of the bonding apparatus, e.g. in the apparatus chuck	<administrative transfer to H10W 72/07178>
D	H01L2224/75725	5	in the upper part of the bonding apparatus, e.g. in the bonding head	<administrative transfer to H10W 72/07178>
D	H01L2224/75733	4	Magnetic holding means	<administrative transfer to H10W 72/07178>
D	H01L2224/75734	5	in the lower part of the bonding apparatus, e.g. in the apparatus chuck	<administrative transfer to H10W 72/07178>
D	H01L2224/75735	5	in the upper part of the bonding apparatus, e.g. in the bonding head	<administrative transfer to H10W 72/07178>
D	H01L2224/75743	4	Suction holding means	<administrative transfer to H10W 72/07178>
D	H01L2224/75744	5	in the lower part of the bonding apparatus, e.g. in the apparatus chuck	<administrative transfer to H10W 72/07178>
D	H01L2224/75745	5	in the upper part of the bonding apparatus, e.g. in the bonding head	<administrative transfer to H10W 72/07178>
D	H01L2224/75753	4	Means for optical alignment, e.g. sensors	<administrative transfer to H10W 72/07178>
D	H01L2224/75754	4	Guiding structures	<administrative transfer to H10W 72/07178>
D	H01L2224/75755	5	in the lower part of the bonding apparatus, e.g. in the apparatus chuck	<administrative transfer to H10W 72/07178>
D	H01L2224/75756	5	in the upper part of the bonding apparatus, e.g. in the bonding head	<administrative transfer to H10W 72/07178>
D	H01L2224/758	3	Means for moving parts	<administrative transfer to H10W 72/07173>
D	H01L2224/75801	4	Lower part of the bonding apparatus, e.g. XY table	<administrative transfer to H10W 72/07173>
D	H01L2224/75802	5	Rotational mechanism	<administrative transfer to H10W 72/07173>
D	H01L2224/75803	6	Pivoting mechanism	<administrative transfer to H10W 72/07173>

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D	H01L2224/75804	5	Translational mechanism	<administrative transfer to H10W 72/07173>
D	H01L2224/75821	4	Upper part of the bonding apparatus, i.e. bonding head	<administrative transfer to H10W 72/07173>
D	H01L2224/75822	5	Rotational mechanism	<administrative transfer to H10W 72/07173>
D	H01L2224/75823	6	Pivoting mechanism	<administrative transfer to H10W 72/07173>
D	H01L2224/75824	5	Translational mechanism	<administrative transfer to H10W 72/07173>
D	H01L2224/75841	4	of the bonding head	<administrative transfer to H10W 72/07173>
D	H01L2224/75842	5	Rotational mechanism	<administrative transfer to H10W 72/07173>
D	H01L2224/75843	6	Pivoting mechanism	<administrative transfer to H10W 72/07173>
D	H01L2224/759	3	Means for monitoring the connection process	<administrative transfer to H10W 72/07183>
D	H01L2224/75901	4	using a computer, e.g. fully- or semi-automatic bonding	<administrative transfer to H10W 72/07183>
D	H01L2224/7592	4	Load or pressure adjusting means, e.g. sensors	<administrative transfer to H10W 72/07183>
D	H01L2224/75925	4	Vibration adjusting means, e.g. sensors	<administrative transfer to H10W 72/07183>
D	H01L2224/7595	3	Means for forming additional members	<administrative transfer to H10W 72/07131>
D	H01L2224/7598	3	pecially adapted for batch processes	<administrative transfer to H10W 72/0711>
D	H01L2224/75981	3	Apparatus chuck	<administrative transfer to H10W 72/07188>
D	H01L2224/75982	4	Shape	<administrative transfer to H10W 72/07188>
D	H01L2224/75983	5	of the mounting surface	<administrative transfer to H10W 72/07188>
D	H01L2224/75984	5	of other portions	<administrative transfer to H10W 72/07188>
D	H01L2224/75985	4	Material	<administrative transfer to H10W 72/07188>
D	H01L2224/75986	4	Auxiliary members on the pressing surface	<administrative transfer to H10W 72/07188>
D	H01L2224/75987	5	Shape of the auxiliary member	<administrative transfer to H10W 72/07188>
D	H01L2224/75988	5	Material of the auxiliary member	<administrative transfer to H10W 72/07188>
D	H01L2224/76	2	Apparatus for connecting with build-up interconnects	<administrative transfer to H10W 72/07188>
D	H01L2224/76001	3	Calibration means	<administrative transfer to H10W 72/0711>

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D	H01L2224/7601	3	Means for cleaning, e.g. brushes, for hydro blasting, for ultrasonic cleaning, for dry ice blasting, using gas-flow, by etching, by applying flux or plasma	<administrative transfer to H10W 72/07118>
D	H01L2224/761	3	Means for controlling the bonding environment, e.g. valves, vacuum pumps	<administrative transfer to H10W 72/07125>
D	H01L2224/76101	4	Chamber	<administrative transfer to H10W 72/07125>
D	H01L2224/76102	5	Vacuum chamber	<administrative transfer to H10W 72/07125>
D	H01L2224/7611	5	High pressure chamber	<administrative transfer to H10W 72/07125>
D	H01L2224/7615	3	Means for depositing	<administrative transfer to H10W 72/07131>
D	H01L2224/76151	4	Means for direct writing	<administrative transfer to H10W 72/07131>
D	H01L2224/76152	5	Syringe	<administrative transfer to H10W 72/07131>
D	H01L2224/76155	5	Jetting means, e.g. ink jet	<administrative transfer to H10W 72/07131>
D	H01L2224/76158	5	including a laser	<administrative transfer to H10W 72/07131>
D	H01L2224/76161	4	Means for screen printing, e.g. roller, squeegee, screen stencil	<administrative transfer to H10W 72/07131>
D	H01L2224/7617	4	Means for applying a preform, e.g. laminator	<administrative transfer to H10W 72/07131>
D	H01L2224/76171	5	including a vacuum-bag	<administrative transfer to H10W 72/07131>
D	H01L2224/7618	4	Means for blanket deposition	<administrative transfer to H10W 72/07131>
D	H01L2224/76181	5	for spin coating, i.e. spin coater	<administrative transfer to H10W 72/07131>
D	H01L2224/76182	5	for curtain coating	<administrative transfer to H10W 72/07131>
D	H01L2224/76183	5	for immersion coating, i.e. bath	<administrative transfer to H10W 72/07131>
D	H01L2224/76184	5	for spray coating, i.e. nozzle	<administrative transfer to H10W 72/07131>
D	H01L2224/76185	5	Means for physical vapour deposition [PVD]	<administrative transfer to H10W 72/07131>
D	H01L2224/76186	6	Means for sputtering, e.g. target	<administrative transfer to H10W 72/07131>
D	H01L2224/76187	6	Means for evaporation	<administrative transfer to H10W 72/07131>
D	H01L2224/76188	5	Means for chemical vapour deposition [CVD], e.g. for laser CVD	<administrative transfer to H10W 72/07131>
D	H01L2224/76189	5	Means for plating, e.g. for electroplating, electroless plating	<administrative transfer to H10W 72/07131>

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D	H01L2224/762	3	Protection means against electrical discharge	<administrative transfer to H10W 72/07139>
D	H01L2224/7625	3	Means for applying energy, e.g. heating means	<administrative transfer to H10W 72/07141>
D	H01L2224/76251	4	in the lower part of the bonding apparatus, e.g. in the apparatus chuck	<administrative transfer to H10W 72/07141>
D	H01L2224/76252	4	in the upper part of the bonding apparatus	<administrative transfer to H10W 72/07141>
D	H01L2224/76253	4	adapted for localised heating	<administrative transfer to H10W 72/07141>
D	H01L2224/7626	4	Polychromatic heating lamp	<administrative transfer to H10W 72/07141>
D	H01L2224/76261	4	Laser	<administrative transfer to H10W 72/07141>
D	H01L2224/76262	5	in the lower part of the bonding apparatus, e.g. in the apparatus chuck	<administrative transfer to H10W 72/07141>
D	H01L2224/76263	5	in the upper part of the bonding apparatus	<administrative transfer to H10W 72/07141>
D	H01L2224/76264	4	by induction heating, i.e. coils	<administrative transfer to H10W 72/07141>
D	H01L2224/76265	5	in the lower part of the bonding apparatus, e.g. in the apparatus chuck	<administrative transfer to H10W 72/07141>
D	H01L2224/76266	5	in the upper part of the bonding apparatus	<administrative transfer to H10W 72/07141>
D	H01L2224/76267	4	Flame torch, e.g. hydrogen torch	<administrative transfer to H10W 72/07141>
D	H01L2224/76268	4	Discharge electrode	<administrative transfer to H10W 72/07141>
D	H01L2224/76269	5	Shape of the discharge electrode	<administrative transfer to H10W 72/07141>
D	H01L2224/7627	5	Material of the discharge electrode	<administrative transfer to H10W 72/07141>
D	H01L2224/76271	5	Circuitry of the discharge electrode	<administrative transfer to H10W 72/07141>
D	H01L2224/76272	4	Oven	<administrative transfer to H10W 72/07141>
D	H01L2224/7628	4	Resistance welding electrodes, i.e. for ohmic heating	<administrative transfer to H10W 72/07141>
D	H01L2224/76281	5	in the lower part of the bonding apparatus, e.g. in the apparatus chuck	<administrative transfer to H10W 72/07141>
D	H01L2224/76282	5	in the upper part of the bonding apparatus	<administrative transfer to H10W 72/07141>
D	H01L2224/76283	4	by infrared heating, e.g. infrared heating lamp	<administrative transfer to H10W 72/07141>
D	H01L2224/763	4	by means of pressure	<administrative transfer to H10W 72/07141>
D	H01L2224/76301	5	Pressing head	<administrative transfer to H10W 72/07141>

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D	H01L2224/76302	6	Shape	<administrative transfer to H10W 72/07141>
D	H01L2224/76303	7	of the pressing surface	<administrative transfer to H10W 72/07141>
D	H01L2224/76304	8	being curved	<administrative transfer to H10W 72/07141>
D	H01L2224/76305	8	comprising protrusions	<administrative transfer to H10W 72/07141>
D	H01L2224/7631	7	of other parts	<administrative transfer to H10W 72/07141>
D	H01L2224/76312	6	Material	<administrative transfer to H10W 72/07141>
D	H01L2224/76313	6	Removable pressing head	<administrative transfer to H10W 72/07141>
D	H01L2224/76314	6	Auxiliary members on the pressing surface	<administrative transfer to H10W 72/07141>
D	H01L2224/76315	7	Elastomer inlay	<administrative transfer to H10W 72/07141>
D	H01L2224/76316	8	with retaining mechanisms	<administrative transfer to H10W 72/07141>
D	H01L2224/76317	7	Removable auxiliary member	<administrative transfer to H10W 72/07141>
D	H01L2224/76318	7	Shape of the auxiliary member	<administrative transfer to H10W 72/07141>
D	H01L2224/7632	7	Material of the auxiliary member	<administrative transfer to H10W 72/07141>
D	H01L2224/76343	5	by ultrasonic vibrations	<administrative transfer to H10W 72/07141>
D	H01L2224/76344	6	Eccentric cams	<administrative transfer to H10W 72/07141>
D	H01L2224/76345	7	in the lower part of the bonding apparatus, e.g. in the apparatus chuck	<administrative transfer to H10W 72/07141>
D	H01L2224/76346	7	in the upper part of the bonding apparatus	<administrative transfer to H10W 72/07141>
D	H01L2224/76347	6	Piezoelectric transducers	<administrative transfer to H10W 72/07141>
D	H01L2224/76348	7	in the lower part of the bonding apparatus, e.g. in the apparatus chuck	<administrative transfer to H10W 72/07141>
D	H01L2224/76349	7	in the upper part of the bonding apparatus	<administrative transfer to H10W 72/07141>
D	H01L2224/7635	6	Stable and mobile yokes	<administrative transfer to H10W 72/07141>
D	H01L2224/76351	7	in the lower part of the bonding apparatus, e.g. in the apparatus chuck	<administrative transfer to H10W 72/07141>
D	H01L2224/76352	7	in the upper part of the bonding apparatus	<administrative transfer to H10W 72/07141>
D	H01L2224/76353	6	Ultrasonic horns	<administrative transfer to H10W 72/07141>

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D	H01L2224/76354	7	in the lower part of the bonding apparatus, e.g. in the apparatus chuck	<administrative transfer to H10W 72/07141>
D	H01L2224/76355	7	Design, e.g. of the wave guide	<administrative transfer to H10W 72/07141>
D	H01L2224/765	3	Cooling means	<administrative transfer to H10W 72/07152>
D	H01L2224/76501	4	in the lower part of the bonding apparatus, e.g. in the apparatus chuck	<administrative transfer to H10W 72/07152>
D	H01L2224/76502	4	in the upper part of the bonding apparatus	<administrative transfer to H10W 72/07152>
D	H01L2224/7655	3	Mechanical means, e.g. for planarising, pressing, stamping	<administrative transfer to H10W 72/07163>
D	H01L2224/76552	4	for drilling	<administrative transfer to H10W 72/07163>
D	H01L2224/76554	4	for abrasive blasting, e.g. sand blasting, wet blasting, hydro-blasting, dry ice blasting	<administrative transfer to H10W 72/07163>
D	H01L2224/766	3	Means for supplying the material of the interconnect	<administrative transfer to H10W 72/07168>
D	H01L2224/76601	4	Storing means	<administrative transfer to H10W 72/07168>
D	H01L2224/76611	4	Feeding means	<administrative transfer to H10W 72/07168>
D	H01L2224/76621	4	Holding means	<administrative transfer to H10W 72/07168>
D	H01L2224/7665	3	Means for transporting the components to be connected	<administrative transfer to H10W 72/07173>
D	H01L2224/76651	4	Belt conveyor	<administrative transfer to H10W 72/07173>
D	H01L2224/76652	4	Chain conveyor	<administrative transfer to H10W 72/07173>
D	H01L2224/76653	4	Vibrating conveyor	<administrative transfer to H10W 72/07173>
D	H01L2224/76654	4	Pneumatic conveyor	<administrative transfer to H10W 72/07173>
D	H01L2224/76655	4	in a fluid	<administrative transfer to H10W 72/07173>
D	H01L2224/767	3	Means for aligning	<administrative transfer to H10W 72/07178>
D	H01L2224/76701	4	in the lower part of the bonding apparatus, e.g. in the apparatus chuck	<administrative transfer to H10W 72/07178>
D	H01L2224/76702	4	in the upper part of the bonding apparatus	<administrative transfer to H10W 72/07178>
D	H01L2224/76703	4	Mechanical holding means	<administrative transfer to H10W 72/07178>
D	H01L2224/76704	5	in the lower part of the bonding apparatus, e.g. in the apparatus chuck	<administrative transfer to H10W 72/07178>
D	H01L2224/76705	5	in the upper part of the bonding apparatus	<administrative transfer to H10W 72/07178>

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D	H01L2224/76723	4	Electrostatic holding means	<administrative transfer to H10W 72/07178>
D	H01L2224/76724	5	in the lower part of the bonding apparatus, e.g. in the apparatus chuck	<administrative transfer to H10W 72/07178>
D	H01L2224/76725	5	in the upper part of the bonding apparatus	<administrative transfer to H10W 72/07178>
D	H01L2224/76733	4	Magnetic holding means	<administrative transfer to H10W 72/07178>
D	H01L2224/76734	5	in the lower part of the bonding apparatus, e.g. in the apparatus chuck	<administrative transfer to H10W 72/07178>
D	H01L2224/76735	5	in the upper part of the bonding apparatus	<administrative transfer to H10W 72/07178>
D	H01L2224/76743	4	Suction holding means	<administrative transfer to H10W 72/07178>
D	H01L2224/76744	5	in the lower part of the bonding apparatus, e.g. in the apparatus chuck	<administrative transfer to H10W 72/07178>
D	H01L2224/76745	5	in the upper part of the bonding apparatus	<administrative transfer to H10W 72/07178>
D	H01L2224/76753	4	Means for optical alignment, e.g. sensors	<administrative transfer to H10W 72/07178>
D	H01L2224/76754	4	Guiding structures	<administrative transfer to H10W 72/07178>
D	H01L2224/76755	5	in the lower part of the bonding apparatus, e.g. in the apparatus chuck	<administrative transfer to H10W 72/07178>
D	H01L2224/76756	5	in the upper part of the bonding apparatus	<administrative transfer to H10W 72/07178>
D	H01L2224/768	3	Means for moving parts	<administrative transfer to H10W 72/07173>
D	H01L2224/76801	4	Lower part of the bonding apparatus, e.g. XY table	<administrative transfer to H10W 72/07173>
D	H01L2224/76802	5	Rotational mechanism	<administrative transfer to H10W 72/07173>
D	H01L2224/76803	6	Pivoting mechanism	<administrative transfer to H10W 72/07173>
D	H01L2224/76804	5	Translational mechanism	<administrative transfer to H10W 72/07173>
D	H01L2224/76821	4	Upper part of the bonding apparatus, i.e. bonding head	<administrative transfer to H10W 72/07173>
D	H01L2224/76822	5	Rotational mechanism	<administrative transfer to H10W 72/07173>
D	H01L2224/76823	6	Pivoting mechanism	<administrative transfer to H10W 72/07173>
D	H01L2224/76824	5	Translational mechanism	<administrative transfer to H10W 72/07173>
D	H01L2224/76841	4	of the bonding head	<administrative transfer to H10W 72/07173>
D	H01L2224/76842	5	Rotational mechanism	<administrative transfer to H10W 72/07173>

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D	H01L2224/76843	6	Pivoting mechanism	<administrative transfer to H10W 72/07173>
D	H01L2224/769	3	Means for monitoring the connection process	<administrative transfer to H10W 72/07183>
D	H01L2224/76901	4	using a computer, e.g. fully- or semi-automatic bonding	<administrative transfer to H10W 72/07183>
D	H01L2224/7692	4	Load or pressure adjusting means, e.g. sensors	<administrative transfer to H10W 72/07183>
D	H01L2224/76925	4	Vibration adjusting means, e.g. sensors	<administrative transfer to H10W 72/07183>
D	H01L2224/7695	3	Means for forming additional members	<administrative transfer to H10W 72/07131>
D	H01L2224/7698	3	specially adapted for batch processes	<administrative transfer to H10W 72/0711>
D	H01L2224/76981	3	Apparatus chuck	<administrative transfer to H10W 72/07188>
D	H01L2224/76982	4	Shape	<administrative transfer to H10W 72/07188>
D	H01L2224/76983	5	of the mounting surface	<administrative transfer to H10W 72/07188>
D	H01L2224/76984	5	of other portions	<administrative transfer to H10W 72/07188>
D	H01L2224/76985	4	Material	<administrative transfer to H10W 72/07188>
D	H01L2224/76986	4	Auxiliary members on the pressing surface	<administrative transfer to H10W 72/07188>
D	H01L2224/76987	5	Shape of the auxiliary member	<administrative transfer to H10W 72/07188>
D	H01L2224/76988	5	Material of the auxiliary member	<administrative transfer to H10W 72/07188>
D	H01L2224/77	2	Apparatus for connecting with strap connectors	<administrative transfer to H10W 72/0711>
D	H01L2224/77001	3	Calibration means	<administrative transfer to H10W 72/07113>
D	H01L2224/7701	3	Means for cleaning, e.g. brushes, for hydro blasting, for ultrasonic cleaning, for dry ice blasting, using gas-flow, by etching, by applying flux or plasma	<administrative transfer to H10W 72/07118>
D	H01L2224/771	3	Means for controlling the bonding environment, e.g. valves, vacuum pumps	<administrative transfer to H10W 72/07125>
D	H01L2224/77101	4	Chamber	<administrative transfer to H10W 72/07125>
D	H01L2224/77102	5	Vacuum chamber	<administrative transfer to H10W 72/07125>
D	H01L2224/7711	5	High pressure chamber	<administrative transfer to H10W 72/07125>
D	H01L2224/7715	3	Means for applying permanent coating, e.g. in-situ coating	<administrative transfer to H10W 72/07131>

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D	H01L2224/77151	4	Means for direct writing	<administrative transfer to H10W 72/07131>
D	H01L2224/77152	5	Syringe	<administrative transfer to H10W 72/07131>
D	H01L2224/77153	6	integrated into the capillary or wedge	<administrative transfer to H10W 72/07131>
D	H01L2224/77155	5	Jetting means, e.g. ink jet	<administrative transfer to H10W 72/07131>
D	H01L2224/77158	5	including a laser	<administrative transfer to H10W 72/07131>
D	H01L2224/77161	4	Means for screen printing, e.g. roller, squeegee, screen stencil	<administrative transfer to H10W 72/07131>
D	H01L2224/7717	4	Means for applying a preform, e.g. laminator	<administrative transfer to H10W 72/07131>
D	H01L2224/77171	5	including a vacuum-bag	<administrative transfer to H10W 72/07131>
D	H01L2224/7718	4	Means for blanket deposition	<administrative transfer to H10W 72/07131>
D	H01L2224/77181	5	for spin coating, i.e. spin coater	<administrative transfer to H10W 72/07131>
D	H01L2224/77182	5	for curtain coating	<administrative transfer to H10W 72/07131>
D	H01L2224/77183	5	for immersion coating, i.e. bath	<administrative transfer to H10W 72/07131>
D	H01L2224/77184	5	for spray coating, i.e. nozzle	<administrative transfer to H10W 72/07131>
D	H01L2224/77185	5	Means for physical vapour deposition [PVD], e.g. evaporation, sputtering	<administrative transfer to H10W 72/07131>
D	H01L2224/77186	5	Means for sputtering, e.g. target	<administrative transfer to H10W 72/07131>
D	H01L2224/77187	5	Means for evaporation	<administrative transfer to H10W 72/07131>
D	H01L2224/77188	5	Means for chemical vapour deposition [CVD], e.g. for laser CVD	<administrative transfer to H10W 72/07131>
D	H01L2224/77189	5	Means for plating, e.g. for electroplating, electroless plating	<administrative transfer to H10W 72/07131>
D	H01L2224/772	3	Protection means against electrical discharge	<administrative transfer to H10W 72/07139>
D	H01L2224/7725	3	Means for applying energy, e.g. heating means	<administrative transfer to H10W 72/07141>
D	H01L2224/77251	4	in the lower part of the bonding apparatus, e.g. in the apparatus chuck	<administrative transfer to H10W 72/07141>
D	H01L2224/77252	4	in the upper part of the bonding apparatus, e.g. in the wedge	<administrative transfer to H10W 72/07141>
D	H01L2224/77253	4	adapted for localised heating	<administrative transfer to H10W 72/07141>
D	H01L2224/7726	4	Polychromatic heating lamp	<administrative transfer to H10W 72/07141>

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D	H01L2224/77261	4	Laser	<administrative transfer to H10W 72/07141>
D	H01L2224/77262	5	in the lower part of the bonding apparatus, e.g. in the apparatus chuck	<administrative transfer to H10W 72/07141>
D	H01L2224/77263	5	in the upper part of the bonding apparatus, e.g. in the wedge	<administrative transfer to H10W 72/07141>
D	H01L2224/77264	4	by induction heating, i.e. coils	<administrative transfer to H10W 72/07141>
D	H01L2224/77265	5	in the lower part of the bonding apparatus, e.g. in the apparatus chuck	<administrative transfer to H10W 72/07141>
D	H01L2224/77266	5	in the upper part of the bonding apparatus, e.g. in the wedge	<administrative transfer to H10W 72/07141>
D	H01L2224/77267	4	Flame torch, e.g. hydrogen torch	<administrative transfer to H10W 72/07141>
D	H01L2224/77268	4	Discharge electrode	<administrative transfer to H10W 72/07141>
D	H01L2224/77269	5	Shape of the discharge electrode	<administrative transfer to H10W 72/07141>
D	H01L2224/7727	5	Material of the discharge electrode	<administrative transfer to H10W 72/07141>
D	H01L2224/77271	5	Circuitry of the discharge electrode	<administrative transfer to H10W 72/07141>
D	H01L2224/77272	4	Oven	<administrative transfer to H10W 72/07141>
D	H01L2224/7728	4	Resistance welding electrodes, i.e. for ohmic heating	<administrative transfer to H10W 72/07141>
D	H01L2224/77281	5	in the lower part of the bonding apparatus, e.g. in the apparatus chuck	<administrative transfer to H10W 72/07141>
D	H01L2224/77282	5	in the upper part of the bonding apparatus, e.g. in the wedge	<administrative transfer to H10W 72/07141>
D	H01L2224/77283	4	by infrared heating, e.g. infrared heating lamp	<administrative transfer to H10W 72/07141>
D	H01L2224/773	4	by means of pressure	<administrative transfer to H10W 72/07141>
D	H01L2224/77313	5	Wedge	<administrative transfer to H10W 72/07141>
D	H01L2224/77314	6	Shape	<administrative transfer to H10W 72/07141>
D	H01L2224/77315	7	of the pressing surface, e.g. tip or head	<administrative transfer to H10W 72/07141>
D	H01L2224/77316	8	comprising protrusions	<administrative transfer to H10W 72/07141>
D	H01L2224/77317	7	of other portions	<administrative transfer to H10W 72/07141>
D	H01L2224/77318	8	inside the capillary	<administrative transfer to H10W 72/07141>
D	H01L2224/77319	8	outside the capillary	<administrative transfer to H10W 72/07141>

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D	H01L2224/7732	6	Removable wedge	<administrative transfer to H10W 72/07141>
D	H01L2224/77321	6	Material	<administrative transfer to H10W 72/07141>
D	H01L2224/77325	6	Auxiliary members on the pressing surface	<administrative transfer to H10W 72/07141>
D	H01L2224/77326	7	Removable auxiliary member	<administrative transfer to H10W 72/07141>
D	H01L2224/77327	7	Shape of the auxiliary member	<administrative transfer to H10W 72/07141>
D	H01L2224/77328	7	Material of the auxiliary member	<administrative transfer to H10W 72/07141>
D	H01L2224/77343	5	by ultrasonic vibrations	<administrative transfer to H10W 72/07141>
D	H01L2224/77344	6	Eccentric cams	<administrative transfer to H10W 72/07141>
D	H01L2224/77345	7	in the lower part of the bonding apparatus, e.g. in the apparatus chuck	<administrative transfer to H10W 72/07141>
D	H01L2224/77346	7	in the upper part of the bonding apparatus, e.g. in the wedge	<administrative transfer to H10W 72/07141>
D	H01L2224/77347	6	Piezoelectric transducers	<administrative transfer to H10W 72/07141>
D	H01L2224/77348	7	in the lower part of the bonding apparatus, e.g. in the apparatus chuck	<administrative transfer to H10W 72/07141>
D	H01L2224/77349	7	in the upper part of the bonding apparatus, e.g. in the wedge	<administrative transfer to H10W 72/07141>
D	H01L2224/7735	6	Stable and mobile yokes	<administrative transfer to H10W 72/07141>
D	H01L2224/77351	7	in the lower part of the bonding apparatus, e.g. in the apparatus chuck	<administrative transfer to H10W 72/07141>
D	H01L2224/77352	7	in the upper part of the bonding apparatus, e.g. in the wedge	<administrative transfer to H10W 72/07141>
D	H01L2224/77353	6	Ultrasonic horns	<administrative transfer to H10W 72/07141>
D	H01L2224/77354	7	in the lower part of the bonding apparatus, e.g. in the mounting chuck	<administrative transfer to H10W 72/07141>
D	H01L2224/77355	7	Design, e.g. of the wave guide	<administrative transfer to H10W 72/07141>
D	H01L2224/775	3	Cooling means	<administrative transfer to H10W 72/07152>
D	H01L2224/77501	4	in the lower part of the bonding apparatus, e.g. in the apparatus chuck	<administrative transfer to H10W 72/07152>
D	H01L2224/77502	4	in the upper part of the bonding apparatus, e.g. in the wedge	<administrative transfer to H10W 72/07152>
D	H01L2224/7755	3	Mechanical means, e.g. for severing, pressing, stamping	<administrative transfer to H10W 72/07163>
D	H01L2224/776	3	Means for supplying the connector to be connected in the bonding apparatus	<administrative transfer to H10W 72/07168>

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D	H01L2224/77601	4	Storing means	<administrative transfer to H10W 72/07168>
D	H01L2224/77611	4	Feeding means	<administrative transfer to H10W 72/07168>
D	H01L2224/77621	4	Holding means, e.g. wire clampers	<administrative transfer to H10W 72/07168>
D	H01L2224/77631	5	Means for wire tension adjustments	<administrative transfer to H10W 72/07168>
D	H01L2224/7765	3	Means for transporting the components to be connected	<administrative transfer to H10W 72/07173>
D	H01L2224/77651	4	Belt conveyor	<administrative transfer to H10W 72/07173>
D	H01L2224/77652	4	Chain conveyor	<administrative transfer to H10W 72/07173>
D	H01L2224/77653	4	Vibrating conveyor	<administrative transfer to H10W 72/07173>
D	H01L2224/77654	4	Pneumatic conveyor	<administrative transfer to H10W 72/07173>
D	H01L2224/77655	4	in a fluid	<administrative transfer to H10W 72/07173>
D	H01L2224/777	3	Means for aligning	<administrative transfer to H10W 72/07178>
D	H01L2224/77701	4	in the lower part of the bonding apparatus, e.g. in the apparatus chuck	<administrative transfer to H10W 72/07178>
D	H01L2224/77702	4	in the upper part of the bonding apparatus, e.g. in the wedge	<administrative transfer to H10W 72/07178>
D	H01L2224/77703	4	Mechanical holding means	<administrative transfer to H10W 72/07178>
D	H01L2224/77704	5	in the lower part of the bonding apparatus, e.g. in the apparatus chuck	<administrative transfer to H10W 72/07178>
D	H01L2224/77705	5	in the upper part of the bonding apparatus, e.g. in the wedge	<administrative transfer to H10W 72/07178>
D	H01L2224/77723	4	Electrostatic holding means	<administrative transfer to H10W 72/07178>
D	H01L2224/77724	5	in the lower part of the bonding apparatus, e.g. in the apparatus chuck	<administrative transfer to H10W 72/07178>
D	H01L2224/77725	5	in the upper part of the bonding apparatus, e.g. in the wedge	<administrative transfer to H10W 72/07178>
D	H01L2224/77733	4	Magnetic holding means	<administrative transfer to H10W 72/07178>
D	H01L2224/77734	5	in the lower part of the bonding apparatus, e.g. in the apparatus chuck	<administrative transfer to H10W 72/07178>
D	H01L2224/77735	5	in the upper part of the bonding apparatus, e.g. in the wedge	<administrative transfer to H10W 72/07178>
D	H01L2224/77743	4	Suction holding means	<administrative transfer to H10W 72/07178>
D	H01L2224/77744	5	in the lower part of the bonding apparatus, e.g. in the apparatus chuck	<administrative transfer to H10W 72/07178>

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D	H01L2224/77745	5	in the upper part of the bonding apparatus, e.g. in the wedge	<administrative transfer to H10W 72/07178>
D	H01L2224/77753	4	Means for optical alignment, e.g. sensors	<administrative transfer to H10W 72/07178>
D	H01L2224/77754	4	Guiding structures	<administrative transfer to H10W 72/07178>
D	H01L2224/77755	5	in the lower part of the bonding apparatus, e.g. in the apparatus chuck	<administrative transfer to H10W 72/07178>
D	H01L2224/77756	5	in the upper part of the bonding apparatus, e.g. in the wedge	<administrative transfer to H10W 72/07178>
D	H01L2224/778	3	Means for moving parts	<administrative transfer to H10W 72/07173>
D	H01L2224/77801	4	Lower part of the bonding apparatus, e.g. XY table	<administrative transfer to H10W 72/07173>
D	H01L2224/77802	5	Rotational mechanism	<administrative transfer to H10W 72/07173>
D	H01L2224/77803	6	Pivoting mechanism	<administrative transfer to H10W 72/07173>
D	H01L2224/77804	5	Translational mechanism	<administrative transfer to H10W 72/07173>
D	H01L2224/77821	4	Upper part of the bonding apparatus, i.e. bonding head, e.g. capillary or wedge	<administrative transfer to H10W 72/07173>
D	H01L2224/77822	5	Rotational mechanism	<administrative transfer to H10W 72/07173>
D	H01L2224/77823	6	Pivoting mechanism	<administrative transfer to H10W 72/07173>
D	H01L2224/77824	5	Translational mechanism	<administrative transfer to H10W 72/07173>
D	H01L2224/77841	4	of the pressing portion, e.g. tip or head	<administrative transfer to H10W 72/07173>
D	H01L2224/77842	5	Rotational mechanism	<administrative transfer to H10W 72/07173>
D	H01L2224/77843	6	Pivoting mechanism	<administrative transfer to H10W 72/07173>
D	H01L2224/779	3	Means for monitoring the connection process	<administrative transfer to H10W 72/07183>
D	H01L2224/77901	4	using a computer, e.g. fully- or semi-automatic bonding	<administrative transfer to H10W 72/07183>
D	H01L2224/7792	4	Load or pressure adjusting means, e.g. sensors	<administrative transfer to H10W 72/07183>
D	H01L2224/77925	4	Vibration adjusting means, e.g. sensors	<administrative transfer to H10W 72/07183>
D	H01L2224/7795	3	Means for forming additional members	<administrative transfer to H10W 72/07131>
D	H01L2224/7798	3	specially adapted for batch processes	<administrative transfer to H10W 72/0711>
D	H01L2224/77981	3	Apparatus chuck	<administrative transfer to H10W 72/07188>

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D	H01L2224/77982	4	Shape	<administrative transfer to H10W 72/07188>
D	H01L2224/77983	5	of the mounting surface	<administrative transfer to H10W 72/07188>
D	H01L2224/77984	5	of other portions	<administrative transfer to H10W 72/07188>
D	H01L2224/77985	4	Material	<administrative transfer to H10W 72/07188>
D	H01L2224/77986	4	Auxiliary members on the pressing surface	<administrative transfer to H10W 72/07188>
D	H01L2224/77987	5	Shape of the auxiliary member	<administrative transfer to H10W 72/07188>
D	H01L2224/77988	5	Material of the auxiliary member	<administrative transfer to H10W 72/07188>
D	H01L2224/78	2	Apparatus for connecting with wire connectors	<administrative transfer to H10W 72/0711>
D	H01L2224/78001	3	Calibration means	<administrative transfer to H10W 72/07113>
D	H01L2224/7801	3	Means for cleaning, e.g. brushes, for hydro blasting, for ultrasonic cleaning, for dry ice blasting, using gas-flow, by etching, by applying flux or plasma	<administrative transfer to H10W 72/07118>
D	H01L2224/781	3	Means for controlling the bonding environment, e.g. valves, vacuum pumps	<administrative transfer to H10W 72/07125>
D	H01L2224/78101	4	Chamber	<administrative transfer to H10W 72/07125>
D	H01L2224/78102	5	Vacuum chamber	<administrative transfer to H10W 72/07125>
D	H01L2224/7811	5	High pressure chamber	<administrative transfer to H10W 72/07125>
D	H01L2224/7815	3	Means for applying permanent coating, e.g. in-situ coating	<administrative transfer to H10W 72/07131>
D	H01L2224/782	3	Protection means against electrical discharge	<administrative transfer to H10W 72/07139>
D	H01L2224/7825	3	Means for applying energy, e.g. heating means	<administrative transfer to H10W 72/07141>
D	H01L2224/78251	4	in the lower part of the bonding apparatus, e.g. in the apparatus chuck	<administrative transfer to H10W 72/07141>
D	H01L2224/78252	4	in the upper part of the bonding apparatus, e.g. in the capillary or wedge	<administrative transfer to H10W 72/07141>
D	H01L2224/78253	4	adapted for localised heating	<administrative transfer to H10W 72/07141>
D	H01L2224/7826	4	Polychromatic heating lamp	<administrative transfer to H10W 72/07141>
D	H01L2224/78261	4	Laser	<administrative transfer to H10W 72/07141>
D	H01L2224/78262	5	in the lower part of the bonding apparatus, e.g. in the apparatus chuck	<administrative transfer to H10W 72/07141>

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D	H01L2224/78263	5	in the upper part of the bonding apparatus, e.g. in the capillary or wedge	<administrative transfer to H10W 72/07141>
D	H01L2224/78264	4	by induction heating, i.e. coils	<administrative transfer to H10W 72/07141>
D	H01L2224/78265	5	in the lower part of the bonding apparatus, e.g. in the apparatus chuck	<administrative transfer to H10W 72/07141>
D	H01L2224/78266	5	in the upper part of the bonding apparatus, e.g. in the capillary or wedge	<administrative transfer to H10W 72/07141>
D	H01L2224/78267	4	Flame torch, e.g. hydrogen torch	<administrative transfer to H10W 72/07141>
D	H01L2224/78268	4	Discharge electrode	<administrative transfer to H10W 72/07141>
D	H01L2224/78269	5	Shape of the discharge electrode	<administrative transfer to H10W 72/07141>
D	H01L2224/7827	5	Material of the discharge electrode	<administrative transfer to H10W 72/07141>
D	H01L2224/78271	5	Circuitry of the discharge electrode	<administrative transfer to H10W 72/07141>
D	H01L2224/78272	4	Oven	<administrative transfer to H10W 72/07141>
D	H01L2224/7828	4	Resistance welding electrodes, i.e. for ohmic heating	<administrative transfer to H10W 72/07141>
D	H01L2224/78281	5	in the lower part of the bonding apparatus, e.g. in the apparatus chuck	<administrative transfer to H10W 72/07141>
D	H01L2224/78282	5	in the upper part of the bonding apparatus, e.g. in the capillary or wedge	<administrative transfer to H10W 72/07141>
D	H01L2224/78283	4	by infrared heating, e.g. infrared heating lamp	<administrative transfer to H10W 72/07141>
D	H01L2224/783	4	by means of pressure	<administrative transfer to H10W 72/07141>
D	H01L2224/78301	5	Capillary	<administrative transfer to H10W 72/07141>
D	H01L2224/78302	6	Shape	<administrative transfer to H10W 72/07141>
D	H01L2224/78303	7	of the pressing surface, e.g. tip or head	<administrative transfer to H10W 72/07141>
D	H01L2224/78304	8	comprising protrusions	<administrative transfer to H10W 72/07141>
D	H01L2224/78305	7	of other portions	<administrative transfer to H10W 72/07141>
D	H01L2224/78306	8	inside the capillary	<administrative transfer to H10W 72/07141>
D	H01L2224/78307	8	outside the capillary	<administrative transfer to H10W 72/07141>
D	H01L2224/78308	6	Removable capillary	<administrative transfer to H10W 72/07141>
D	H01L2224/78309	6	Material	<administrative transfer to H10W 72/07141>

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D	H01L2224/7831	6	Auxiliary members on the pressing surface	<administrative transfer to H10W 72/07141>
D	H01L2224/78311	7	Removable auxiliary member	<administrative transfer to H10W 72/07141>
D	H01L2224/78312	7	Shape of the auxiliary member	<administrative transfer to H10W 72/07141>
D	H01L2224/78313	5	Wedge	<administrative transfer to H10W 72/07141>
D	H01L2224/78314	6	Shape	<administrative transfer to H10W 72/07141>
D	H01L2224/78315	7	of the pressing surface, e.g. tip or head	<administrative transfer to H10W 72/07141>
D	H01L2224/78316	8	comprising protrusions	<administrative transfer to H10W 72/07141>
D	H01L2224/78317	7	of other portions	<administrative transfer to H10W 72/07141>
D	H01L2224/78318	8	inside the capillary	<administrative transfer to H10W 72/07141>
D	H01L2224/78319	8	outside the capillary	<administrative transfer to H10W 72/07141>
D	H01L2224/7832	6	Removable wedge	<administrative transfer to H10W 72/07141>
D	H01L2224/78321	6	Material	<administrative transfer to H10W 72/07141>
D	H01L2224/78325	6	Auxiliary members on the pressing surface	<administrative transfer to H10W 72/07141>
D	H01L2224/78326	7	Removable auxiliary member	<administrative transfer to H10W 72/07141>
D	H01L2224/78327	7	Shape of the auxiliary member	<administrative transfer to H10W 72/07141>
D	H01L2224/78328	7	Material of the auxiliary member	<administrative transfer to H10W 72/07141>
D	H01L2224/78343	5	by ultrasonic vibrations	<administrative transfer to H10W 72/07141>
D	H01L2224/78344	6	Eccentric cams	<administrative transfer to H10W 72/07141>
D	H01L2224/78345	7	in the lower part of the bonding apparatus, e.g. in the apparatus chuck	<administrative transfer to H10W 72/07141>
D	H01L2224/78346	7	in the upper part of the bonding apparatus, e.g. in the capillary or wedge	<administrative transfer to H10W 72/07141>
D	H01L2224/78347	6	Piezoelectric transducers	<administrative transfer to H10W 72/07141>
D	H01L2224/78348	7	in the lower part of the bonding apparatus, e.g. in the apparatus chuck	<administrative transfer to H10W 72/07141>
D	H01L2224/78349	7	in the upper part of the bonding apparatus, e.g. in the capillary or wedge	<administrative transfer to H10W 72/07141>
D	H01L2224/7835	6	Stable and mobile yokes	<administrative transfer to H10W 72/07141>

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D	H01L2224/78351	7	in the lower part of the bonding apparatus, e.g. in the apparatus chuck	<administrative transfer to H10W 72/07141>
D	H01L2224/78352	7	in the upper part of the bonding apparatus, e.g. in the capillary or wedge	<administrative transfer to H10W 72/07141>
D	H01L2224/78353	6	Ultrasonic horns	<administrative transfer to H10W 72/07141>
D	H01L2224/78354	7	in the lower part of the bonding apparatus, e.g. in the mounting chuck	<administrative transfer to H10W 72/07141>
D	H01L2224/78355	7	Design, e.g. of the wave guide	<administrative transfer to H10W 72/07141>
D	H01L2224/785	3	Cooling means	<administrative transfer to H10W 72/07152>
D	H01L2224/78501	4	in the lower part of the bonding apparatus, e.g. in the apparatus chuck	<administrative transfer to H10W 72/07152>
D	H01L2224/78502	4	in the upper part of the bonding apparatus, e.g. in the capillary or wedge	<administrative transfer to H10W 72/07152>
D	H01L2224/7855	3	Mechanical means, e.g. for severing, pressing, stamping	<administrative transfer to H10W 72/07163>
D	H01L2224/786	3	Means for supplying the connector to be connected in the bonding apparatus	<administrative transfer to H10W 72/07168>
D	H01L2224/78601	4	Storing means	<administrative transfer to H10W 72/07168>
D	H01L2224/78611	4	Feeding means	<administrative transfer to H10W 72/07168>
D	H01L2224/78621	4	Holding means, e.g. wire clampers	<administrative transfer to H10W 72/07168>
D	H01L2224/78631	5	Means for wire tension adjustments	<administrative transfer to H10W 72/07168>
D	H01L2224/7865	3	Means for transporting the components to be connected	<administrative transfer to H10W 72/07173>
D	H01L2224/78651	4	Belt conveyor	<administrative transfer to H10W 72/07173>
D	H01L2224/78652	4	Chain conveyor	<administrative transfer to H10W 72/07173>
D	H01L2224/78653	4	Vibrating conveyor	<administrative transfer to H10W 72/07173>
D	H01L2224/78654	4	Pneumatic conveyor	<administrative transfer to H10W 72/07173>
D	H01L2224/78655	4	in a fluid	<administrative transfer to H10W 72/07173>
D	H01L2224/787	3	Means for aligning	<administrative transfer to H10W 72/07178>
D	H01L2224/78701	4	in the lower part of the bonding apparatus, e.g. in the apparatus chuck	<administrative transfer to H10W 72/07178>
D	H01L2224/78702	4	in the upper part of the bonding apparatus, e.g. in the capillary or wedge	<administrative transfer to H10W 72/07178>
D	H01L2224/78703	4	Mechanical holding means	<administrative transfer to H10W 72/07178>

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D	H01L2224/78704	5	in the lower part of the bonding apparatus, e.g. in the apparatus chuck	<administrative transfer to H10W 72/07178>
D	H01L2224/78705	5	in the upper part of the bonding apparatus, e.g. in the capillary or wedge	<administrative transfer to H10W 72/07178>
D	H01L2224/78723	4	Electrostatic holding means	<administrative transfer to H10W 72/07178>
D	H01L2224/78724	5	in the lower part of the bonding apparatus, e.g. in the apparatus chuck	<administrative transfer to H10W 72/07178>
D	H01L2224/78725	5	in the upper part of the bonding apparatus, e.g. in the capillary or wedge	<administrative transfer to H10W 72/07178>
D	H01L2224/78733	4	Magnetic holding means	<administrative transfer to H10W 72/07178>
D	H01L2224/78734	5	in the lower part of the bonding apparatus, e.g. in the apparatus chuck	<administrative transfer to H10W 72/07178>
D	H01L2224/78735	5	in the upper part of the bonding apparatus, e.g. in the capillary or wedge	<administrative transfer to H10W 72/07178>
D	H01L2224/78743	4	Suction holding means	<administrative transfer to H10W 72/07178>
D	H01L2224/78744	5	in the lower part of the bonding apparatus, e.g. in the apparatus chuck	<administrative transfer to H10W 72/07178>
D	H01L2224/78745	5	in the upper part of the bonding apparatus, e.g. in the capillary or wedge	<administrative transfer to H10W 72/07178>
D	H01L2224/78753	4	Means for optical alignment, e.g. sensors	<administrative transfer to H10W 72/07178>
D	H01L2224/78754	4	Guiding structures	<administrative transfer to H10W 72/07178>
D	H01L2224/78755	5	in the lower part of the bonding apparatus, e.g. in the apparatus chuck	<administrative transfer to H10W 72/07178>
D	H01L2224/78756	5	in the upper part of the bonding apparatus, e.g. in the capillary or wedge	<administrative transfer to H10W 72/07178>
D	H01L2224/788	3	Means for moving parts	<administrative transfer to H10W 72/07173>
D	H01L2224/78801	4	Lower part of the bonding apparatus, e.g. XY table	<administrative transfer to H10W 72/07173>
D	H01L2224/78802	5	Rotational mechanism	<administrative transfer to H10W 72/07173>
D	H01L2224/78803	6	Pivoting mechanism	<administrative transfer to H10W 72/07173>
D	H01L2224/78804	5	Translational mechanism	<administrative transfer to H10W 72/07173>
D	H01L2224/78821	4	Upper part of the bonding apparatus, i.e. bonding head, e.g. capillary or wedge	<administrative transfer to H10W 72/07173>
D	H01L2224/78822	5	Rotational mechanism	<administrative transfer to H10W 72/07173>
D	H01L2224/78823	6	Pivoting mechanism	<administrative transfer to H10W 72/07173>
D	H01L2224/78824	5	Translational mechanism	<administrative transfer to H10W 72/07173>

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D	H01L2224/78841	4	of the pressing portion, e.g. tip or head	<administrative transfer to H10W 72/07173>
D	H01L2224/78842	5	Rotational mechanism	<administrative transfer to H10W 72/07173>
D	H01L2224/78843	6	Pivoting mechanism	<administrative transfer to H10W 72/07173>
D	H01L2224/789	3	Means for monitoring the connection process	<administrative transfer to H10W 72/07183>
D	H01L2224/78901	4	using a computer, e.g. fully- or semi-automatic bonding	<administrative transfer to H10W 72/07183>
D	H01L2224/7892	4	Load or pressure adjusting means, e.g. sensors	<administrative transfer to H10W 72/07183>
D	H01L2224/78925	4	Vibration adjusting means, e.g. sensors	<administrative transfer to H10W 72/07183>
D	H01L2224/7895	3	Means for forming additional members	<administrative transfer to H10W 72/07131>
D	H01L2224/7898	3	specially adapted for batch processes	<administrative transfer to H10W 72/0711>
D	H01L2224/78981	3	Apparatus chuck	<administrative transfer to H10W 72/07188>
D	H01L2224/78982	4	Shape	<administrative transfer to H10W 72/07188>
D	H01L2224/78983	5	of the mounting surface	<administrative transfer to H10W 72/07188>
D	H01L2224/78984	5	of other portions	<administrative transfer to H10W 72/07188>
D	H01L2224/78985	4	Material	<administrative transfer to H10W 72/07188>
D	H01L2224/78986	4	Auxiliary members on the pressing surface	<administrative transfer to H10W 72/07188>
D	H01L2224/78987	5	Shape of the auxiliary member	<administrative transfer to H10W 72/07188>
D	H01L2224/78988	5	Material of the auxiliary member	<administrative transfer to H10W 72/07188>
D	H01L2224/79	2	Apparatus for Tape Automated Bonding [TAB]	<administrative transfer to H10W 72/0711>
D	H01L2224/79001	3	Calibration means	<administrative transfer to H10W 72/07113>
D	H01L2224/7901	3	Means for cleaning, e.g. brushes, for hydro blasting, for ultrasonic cleaning, for dry ice blasting, using gas-flow, by etching, by applying flux or plasma	<administrative transfer to H10W 72/07118>
D	H01L2224/791	3	Means for controlling the bonding environment, e.g. valves, vacuum pumps	<administrative transfer to H10W 72/07125>
D	H01L2224/79101	4	Chamber	<administrative transfer to H10W 72/07125>
D	H01L2224/79102	5	Vacuum chamber	<administrative transfer to H10W 72/07125>

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D	H01L2224/7911	5	High pressure chamber	<administrative transfer to H10W 72/07125>
D	H01L2224/7915	3	Means for applying permanent coating	<administrative transfer to H10W 72/07131>
D	H01L2224/79151	4	Means for direct writing	<administrative transfer to H10W 72/07131>
D	H01L2224/79152	5	Syringe	<administrative transfer to H10W 72/07131>
D	H01L2224/79153	6	integrated into the pressing head	<administrative transfer to H10W 72/07131>
D	H01L2224/79155	5	Jetting means, e.g. ink jet	<administrative transfer to H10W 72/07131>
D	H01L2224/79158	5	including a laser	<administrative transfer to H10W 72/07131>
D	H01L2224/79161	4	Means for screen printing, e.g. roller, squeegee, screen stencil	<administrative transfer to H10W 72/07131>
D	H01L2224/7917	4	Means for applying a preform, e.g. laminator	<administrative transfer to H10W 72/07131>
D	H01L2224/79171	5	including a vacuum-bag	<administrative transfer to H10W 72/07131>
D	H01L2224/7918	4	Means for blanket deposition	<administrative transfer to H10W 72/07131>
D	H01L2224/79181	5	for spin coating, i.e. spin coater	<administrative transfer to H10W 72/07131>
D	H01L2224/79182	5	for curtain coating	<administrative transfer to H10W 72/07131>
D	H01L2224/79183	5	for immersion coating, i.e. bath	<administrative transfer to H10W 72/07131>
D	H01L2224/79184	5	for spray coating, i.e. nozzle	<administrative transfer to H10W 72/07131>
D	H01L2224/79185	5	Means for physical vapour deposition [PVD], e.g. evaporation, sputtering	<administrative transfer to H10W 72/07131>
D	H01L2224/79186	5	Means for sputtering, e.g. target	<administrative transfer to H10W 72/07131>
D	H01L2224/79187	5	Means for evaporation	<administrative transfer to H10W 72/07131>
D	H01L2224/79188	5	Means for chemical vapour deposition [CVD], e.g. for laser CVD	<administrative transfer to H10W 72/07131>
D	H01L2224/79189	5	Means for plating, e.g. for electroplating, electroless plating	<administrative transfer to H10W 72/07131>
D	H01L2224/792	3	Protection means against electrical discharge	<administrative transfer to H10W 72/07139>
D	H01L2224/7925	3	Means for applying energy, e.g. heating means	<administrative transfer to H10W 72/07141>
D	H01L2224/79251	4	in the lower part of the bonding apparatus, e.g. in the apparatus chuck	<administrative transfer to H10W 72/07141>
D	H01L2224/79252	4	in the upper part of the bonding apparatus, e.g. in the pressing head	<administrative transfer to H10W 72/07141>

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D	H01L2224/79253	4	adapted for localised heating	<administrative transfer to H10W 72/07141>
D	H01L2224/7926	4	Polychromatic heating lamp	<administrative transfer to H10W 72/07141>
D	H01L2224/79261	4	Laser	<administrative transfer to H10W 72/07141>
D	H01L2224/79262	5	in the lower part of the bonding apparatus, e.g. in the apparatus chuck	<administrative transfer to H10W 72/07141>
D	H01L2224/79263	5	in the upper part of the bonding apparatus, e.g. in the pressing head	<administrative transfer to H10W 72/07141>
D	H01L2224/79264	4	by induction heating, i.e. coils	<administrative transfer to H10W 72/07141>
D	H01L2224/79265	5	in the lower part of the bonding apparatus, e.g. in the apparatus chuck	<administrative transfer to H10W 72/07141>
D	H01L2224/79266	5	in the upper part of the bonding apparatus, e.g. in the pressing head	<administrative transfer to H10W 72/07141>
D	H01L2224/79267	4	Flame torch, e.g. hydrogen torch	<administrative transfer to H10W 72/07141>
D	H01L2224/79268	4	Discharge electrode	<administrative transfer to H10W 72/07141>
D	H01L2224/79269	5	Shape of the discharge electrode	<administrative transfer to H10W 72/07141>
D	H01L2224/7927	5	Material of the discharge electrode	<administrative transfer to H10W 72/07141>
D	H01L2224/79271	5	Circuitry of the discharge electrode	<administrative transfer to H10W 72/07141>
D	H01L2224/79272	4	Oven	<administrative transfer to H10W 72/07141>
D	H01L2224/7928	4	Resistance welding electrodes, i.e. for ohmic heating	<administrative transfer to H10W 72/07141>
D	H01L2224/79281	5	in the lower part of the bonding apparatus, e.g. in the apparatus chuck	<administrative transfer to H10W 72/07141>
D	H01L2224/79282	5	in the upper part of the bonding apparatus, e.g. in the pressing head	<administrative transfer to H10W 72/07141>
D	H01L2224/79283	4	by infrared heating, e.g. infrared heating lamp	<administrative transfer to H10W 72/07141>
D	H01L2224/793	4	by means of pressure	<administrative transfer to H10W 72/07141>
D	H01L2224/79301	5	Pressing head	<administrative transfer to H10W 72/07141>
D	H01L2224/79302	6	Shape	<administrative transfer to H10W 72/07141>
D	H01L2224/79303	7	of the pressing surface	<administrative transfer to H10W 72/07141>
D	H01L2224/79304	8	being curved	<administrative transfer to H10W 72/07141>
D	H01L2224/79305	8	comprising protrusions	<administrative transfer to H10W 72/07141>

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D	H01L2224/7931	7	of other parts	<administrative transfer to H10W 72/07141>
D	H01L2224/79312	6	Material	<administrative transfer to H10W 72/07141>
D	H01L2224/79313	6	Removable pressing head	<administrative transfer to H10W 72/07141>
D	H01L2224/79314	6	Auxiliary members on the pressing surface	<administrative transfer to H10W 72/07141>
D	H01L2224/79315	7	Elastomer inlay	<administrative transfer to H10W 72/07141>
D	H01L2224/79316	8	with retaining mechanisms	<administrative transfer to H10W 72/07141>
D	H01L2224/79317	7	Removable auxiliary member	<administrative transfer to H10W 72/07141>
D	H01L2224/79318	7	Shape of the auxiliary member	<administrative transfer to H10W 72/07141>
D	H01L2224/7932	7	Material of the auxiliary member	<administrative transfer to H10W 72/07141>
D	H01L2224/79343	5	by ultrasonic vibrations	<administrative transfer to H10W 72/07141>
D	H01L2224/79344	6	Eccentric cams	<administrative transfer to H10W 72/07141>
D	H01L2224/79345	7	in the lower part of the bonding apparatus, e.g. in the apparatus chuck	<administrative transfer to H10W 72/07141>
D	H01L2224/79346	7	in the upper part of the bonding apparatus, e.g. in the pressing head	<administrative transfer to H10W 72/07141>
D	H01L2224/79347	6	Piezoelectric transducers	<administrative transfer to H10W 72/07141>
D	H01L2224/79348	7	in the lower part of the bonding apparatus, e.g. in the apparatus chuck	<administrative transfer to H10W 72/07141>
D	H01L2224/79349	7	in the upper part of the bonding apparatus, e.g. in the pressing head	<administrative transfer to H10W 72/07141>
D	H01L2224/7935	6	Stable and mobile yokes	<administrative transfer to H10W 72/07141>
D	H01L2224/79351	7	in the lower part of the bonding apparatus, e.g. in the apparatus chuck	<administrative transfer to H10W 72/07141>
D	H01L2224/79352	7	in the upper part of the bonding apparatus, e.g. in the pressing head	<administrative transfer to H10W 72/07141>
D	H01L2224/79353	6	Ultrasonic horns	<administrative transfer to H10W 72/07141>
D	H01L2224/79354	7	in the lower part of the bonding apparatus, e.g. in the apparatus chuck	<administrative transfer to H10W 72/07141>
D	H01L2224/79355	7	Design, e.g. of the wave guide	<administrative transfer to H10W 72/07141>
D	H01L2224/795	3	Cooling means	<administrative transfer to H10W 72/07152>
D	H01L2224/79501	4	in the lower part of the bonding apparatus, e.g. in the apparatus chuck	<administrative transfer to H10W 72/07152>

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D	H01L2224/79502	4	in the upper part of the bonding apparatus, e.g. in the pressing head	<administrative transfer to H10W 72/07152>
D	H01L2224/7955	3	Mechanical means, e.g. for pressing, stamping	<administrative transfer to H10W 72/07163>
D	H01L2224/796	3	Means for supplying the connector to be connected in the bonding apparatus	<administrative transfer to H10W 72/07168>
D	H01L2224/79601	4	Storing means	<administrative transfer to H10W 72/07168>
D	H01L2224/79611	4	Feeding means	<administrative transfer to H10W 72/07168>
D	H01L2224/79621	4	Holding means	<administrative transfer to H10W 72/07168>
D	H01L2224/7965	3	Means for transporting the components to be connected	<administrative transfer to H10W 72/07173>
D	H01L2224/79651	4	Belt conveyor	<administrative transfer to H10W 72/07173>
D	H01L2224/79652	4	Chain conveyor	<administrative transfer to H10W 72/07173>
D	H01L2224/79653	4	Vibrating conveyor	<administrative transfer to H10W 72/07173>
D	H01L2224/79654	4	Pneumatic conveyor	<administrative transfer to H10W 72/07173>
D	H01L2224/79655	4	in a fluid	<administrative transfer to H10W 72/07173>
D	H01L2224/797	3	Means for aligning	<administrative transfer to H10W 72/07178>
D	H01L2224/79701	4	in the lower part of the bonding apparatus, e.g. in the apparatus chuck	<administrative transfer to H10W 72/07178>
D	H01L2224/79702	4	in the upper part of the bonding apparatus, e.g. in the pressing head	<administrative transfer to H10W 72/07178>
D	H01L2224/79703	4	Mechanical holding means	<administrative transfer to H10W 72/07178>
D	H01L2224/79704	5	in the lower part of the bonding apparatus, e.g. in the apparatus chuck	<administrative transfer to H10W 72/07178>
D	H01L2224/79705	5	in the upper part of the bonding apparatus, e.g. in the pressing head	<administrative transfer to H10W 72/07178>
D	H01L2224/79723	4	Electrostatic holding means	<administrative transfer to H10W 72/07178>
D	H01L2224/79724	5	in the lower part of the bonding apparatus, e.g. in the apparatus chuck	<administrative transfer to H10W 72/07178>
D	H01L2224/79725	5	in the upper part of the bonding apparatus, e.g. in the pressing head	<administrative transfer to H10W 72/07178>
D	H01L2224/79733	4	Magnetic holding means	<administrative transfer to H10W 72/07178>
D	H01L2224/79734	5	in the lower part of the bonding apparatus, e.g. in the apparatus chuck	<administrative transfer to H10W 72/07178>
D	H01L2224/79735	5	in the upper part of the bonding apparatus, e.g. in the pressing head	<administrative transfer to H10W 72/07178>

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D	H01L2224/79743	4	Suction holding means	<administrative transfer to H10W 72/07178>
D	H01L2224/79744	5	in the lower part of the bonding apparatus, e.g. in the apparatus chuck	<administrative transfer to H10W 72/07178>
D	H01L2224/79745	5	in the upper part of the bonding apparatus, e.g. in the pressing head	<administrative transfer to H10W 72/07178>
D	H01L2224/79753	4	Means for optical alignment, e.g. sensors	<administrative transfer to H10W 72/07178>
D	H01L2224/79754	4	Guiding structures	<administrative transfer to H10W 72/07178>
D	H01L2224/79755	5	in the lower part of the bonding apparatus, e.g. in the apparatus chuck	<administrative transfer to H10W 72/07178>
D	H01L2224/79756	5	in the upper part of the bonding apparatus, e.g. in the pressing head	<administrative transfer to H10W 72/07178>
D	H01L2224/798	3	Means for moving parts	<administrative transfer to H10W 72/07173>
D	H01L2224/79801	4	Lower part of the bonding apparatus, e.g. XY table	<administrative transfer to H10W 72/07173>
D	H01L2224/79802	5	Rotational mechanism	<administrative transfer to H10W 72/07173>
D	H01L2224/79803	6	Pivoting mechanism	<administrative transfer to H10W 72/07173>
D	H01L2224/79804	5	Translational mechanism	<administrative transfer to H10W 72/07173>
D	H01L2224/79821	4	Upper part of the bonding apparatus, i.e. pressing head	<administrative transfer to H10W 72/07173>
D	H01L2224/79822	5	Rotational mechanism	<administrative transfer to H10W 72/07173>
D	H01L2224/79823	6	Pivoting mechanism	<administrative transfer to H10W 72/07173>
D	H01L2224/79824	5	Translational mechanism	<administrative transfer to H10W 72/07173>
D	H01L2224/79841	4	of the pressing head	<administrative transfer to H10W 72/07173>
D	H01L2224/79842	5	Rotational mechanism	<administrative transfer to H10W 72/07173>
D	H01L2224/79843	6	Pivoting mechanism	<administrative transfer to H10W 72/07173>
D	H01L2224/799	3	Means for monitoring the connection process	<administrative transfer to H10W 72/07183>
D	H01L2224/79901	4	using a computer, e.g. fully- or semi-automatic bonding	<administrative transfer to H10W 72/07183>
D	H01L2224/7992	4	Load or pressure adjusting means, e.g. sensors	<administrative transfer to H10W 72/07183>
D	H01L2224/79925	4	Vibration adjusting means, e.g. sensors	<administrative transfer to H10W 72/07183>
D	H01L2224/7995	3	Means for forming additional members	<administrative transfer to H10W 72/07131>

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D	H01L2224/7998	3	especially adapted for batch processes	<administrative transfer to H10W 72/0711>
D	H01L2224/79981	3	Apparatus chuck	<administrative transfer to H10W 72/07188>
D	H01L2224/79982	4	Shape	<administrative transfer to H10W 72/07188>
D	H01L2224/79983	5	of the mounting surface	<administrative transfer to H10W 72/07188>
D	H01L2224/79984	5	of other portions	<administrative transfer to H10W 72/07188>
D	H01L2224/79985	4	Material	<administrative transfer to H10W 72/07188>
D	H01L2224/79986	4	Auxiliary members on the pressing surface	<administrative transfer to H10W 72/07188>
D	H01L2224/79987	5	Shape of the auxiliary member	<administrative transfer to H10W 72/07188>
D	H01L2224/79988	5	Material of the auxiliary member	<administrative transfer to H10W 72/07188>
D	H01L2224/7999	2	for disconnecting	<administrative transfer to H10W 72/0711>
D	H01L2224/80	1	Methods for connecting semiconductor or other solid state bodies using means for bonding being attached to, or being formed on, the surface to be connected	<administrative transfer to H10W 99/00>
D	H01L2224/80001	2	by connecting a bonding area directly to another bonding area, i.e. connectorless bonding, e.g. bumpless bonding	<administrative transfer to H10W 80/00>
D	H01L2224/80003	3	involving a temporary auxiliary member not forming part of the bonding apparatus	<administrative transfer to H10W 80/211>
D	H01L2224/80004	4	being a removable or sacrificial coating	<administrative transfer to H10W 80/211>
D	H01L2224/80006	4	being a temporary or sacrificial substrate	<administrative transfer to H10W 80/211>
D	H01L2224/80007	3	involving a permanent auxiliary member being left in the finished device, e.g. aids for protecting the bonding area during or after the bonding process	<administrative transfer to H10W 80/211>
D	H01L2224/80009	3	Pre-treatment of the bonding area	<administrative transfer to H10W 80/011>
D	H01L2224/8001	4	Cleaning the bonding area, e.g. oxide removal step, desmearing	<administrative transfer to H10W 80/016>
D	H01L2224/80011	5	Chemical cleaning, e.g. etching, flux	<administrative transfer to H10W 80/016>
D	H01L2224/80012	5	Mechanical cleaning, e.g. abrasion using hydro blasting, brushes, ultrasonic cleaning, dry ice blasting, gas-flow	<administrative transfer to H10W 80/016>
D	H01L2224/80013	5	Plasma cleaning	<administrative transfer to H10W 80/016>

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D	H01L2224/80014	5	Thermal cleaning, e.g. decomposition, sublimation	<administrative transfer to H10W 80/016>
D	H01L2224/80019	5	Combinations of two or more cleaning methods provided for in at least two different groups from H01L2224/8001 - H01L2224/80014	<administrative transfer to H10W 80/016>
D	H01L2224/8002	4	Applying permanent coating to the bonding area in the bonding apparatus, e.g. in-situ coating	<administrative transfer to H10W 80/023>
D	H01L2224/80024	4	Applying flux to the bonding area in the bonding apparatus	<administrative transfer to H10W 80/011>
D	H01L2224/8003	4	Reshaping the bonding area in the bonding apparatus, e.g. flattening the bonding area	<administrative transfer to H10W 80/031>
D	H01L2224/80031	5	by chemical means, e.g. etching, anodisation	<administrative transfer to H10W 80/033>
D	H01L2224/80035	5	by heating means	<administrative transfer to H10W 80/035>
D	H01L2224/80037	6	using a polychromatic heating lamp	<administrative transfer to H10W 80/035>
D	H01L2224/80039	6	using a laser	<administrative transfer to H10W 80/035>
D	H01L2224/80041	6	Induction heating, i.e. eddy currents	<administrative transfer to H10W 80/035>
D	H01L2224/80047	5	by mechanical means, e.g. severing, pressing, stamping	<administrative transfer to H10W 80/037>
D	H01L2224/80048	4	Thermal treatments, e.g. annealing, controlled pre-heating or pre-cooling	<administrative transfer to H10W 80/041>
D	H01L2224/80051	4	Forming additional members	<administrative transfer to H10W 80/011>
D	H01L2224/80052	3	Detaching bonding areas, e.g. after testing	<administrative transfer to H10W 80/011>
D	H01L2224/80053	3	Bonding environment	<administrative transfer to H10W 80/102>
D	H01L2224/80054	4	Composition of the atmosphere	<administrative transfer to H10W 80/102>
D	H01L2224/80055	5	being oxidating	<administrative transfer to H10W 80/102>
D	H01L2224/80065	5	being reducing	<administrative transfer to H10W 80/102>
D	H01L2224/80075	5	being inert	<administrative transfer to H10W 80/102>
D	H01L2224/80085	4	being a liquid, e.g. for fluidic self-assembly	<administrative transfer to H10W 80/102>
D	H01L2224/8009	4	Vacuum	<administrative transfer to H10W 80/102>
D	H01L2224/80091	4	Under pressure	<administrative transfer to H10W 80/102>

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D	H01L2224/80092	5	Atmospheric pressure	<administrative transfer to H10W 80/102>
D	H01L2224/80093	5	Transient conditions, e.g. gas-flow	<administrative transfer to H10W 80/102>
D	H01L2224/80095	4	Temperature settings	<administrative transfer to H10W 80/102>
D	H01L2224/80096	5	Transient conditions	<administrative transfer to H10W 80/102>
D	H01L2224/80097	6	Heating	<administrative transfer to H10W 80/102>
D	H01L2224/80098	6	Cooling	<administrative transfer to H10W 80/102>
D	H01L2224/80099	5	Ambient temperature	<administrative transfer to H10W 80/102>
D	H01L2224/8011	3	involving protection against electrical discharge, e.g. removing electrostatic charge	<administrative transfer to H10W 80/011>
D	H01L2224/8012	3	Aligning	<administrative transfer to H10W 80/161>
D	H01L2224/80121	4	Active alignment, i.e. by apparatus steering, e.g. optical alignment using marks or sensors	<administrative transfer to H10W 80/163>
D	H01L2224/80122	5	by detecting inherent features of, or outside, the semiconductor or solid-state body	<administrative transfer to H10W 80/163>
D	H01L2224/80123	6	Shape or position of the body	<administrative transfer to H10W 80/163>
D	H01L2224/80125	6	Bonding areas on the body	<administrative transfer to H10W 80/163>
D	H01L2224/80127	6	Bonding areas outside the body	<administrative transfer to H10W 80/163>
D	H01L2224/80129	6	Shape or position of the other item	<administrative transfer to H10W 80/163>
D	H01L2224/8013	5	using marks formed on the semiconductor or solid-state body	<administrative transfer to H10W 80/163>
D	H01L2224/80132	5	using marks formed outside the semiconductor or solid-state body, i.e. "off-chip"	<administrative transfer to H10W 80/163>
D	H01L2224/80136	4	involving guiding structures, e.g. spacers or supporting members	<administrative transfer to H10W 80/168>
D	H01L2224/80138	5	the guiding structures being at least partially left in the finished device	<administrative transfer to H10W 80/168>
D	H01L2224/80139	6	Guiding structures on the body	<administrative transfer to H10W 80/168>
D	H01L2224/8014	6	Guiding structures outside the body	<administrative transfer to H10W 80/168>
D	H01L2224/80141	6	Guiding structures both on and outside the body	<administrative transfer to H10W 80/168>
D	H01L2224/80143	4	Passive alignment, i.e. self alignment, e.g. using surface energy, chemical reactions, thermal equilibrium	<administrative transfer to H10W 80/165>

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D	H01L2224/80148	4	involving movement of a part of the bonding apparatus	<administrative transfer to H10W 80/161>
D	H01L2224/80149	5	being the lower part of the bonding apparatus, i.e. holding means for the bodies to be connected, e.g. XY table	<administrative transfer to H10W 80/161>
D	H01L2224/8015	6	Rotational movements	<administrative transfer to H10W 80/161>
D	H01L2224/8016	6	Translational movements	<administrative transfer to H10W 80/161>
D	H01L2224/80169	5	being the upper part of the bonding apparatus, i.e. bonding head	<administrative transfer to H10W 80/161>
D	H01L2224/8017	6	Rotational movements	<administrative transfer to H10W 80/161>
D	H01L2224/8018	6	Translational movements	<administrative transfer to H10W 80/161>
D	H01L2224/8019	3	Arrangement of the bonding areas prior to mounting	<administrative transfer to H10W 80/011>
D	H01L2224/80194	4	Lateral distribution of the bonding areas	<administrative transfer to H10W 80/011>
D	H01L2224/802	3	Applying energy for connecting	<administrative transfer to H10W 80/331>
D	H01L2224/80201	4	Compression bonding	<administrative transfer to H10W 80/333>
D	H01L2224/80203	5	Thermocompression bonding, e.g. diffusion bonding, pressure joining, thermocompression welding or solid-state welding	<administrative transfer to H10W 80/334>
D	H01L2224/80204	6	with a graded temperature profile	<administrative transfer to H10W 80/334>
D	H01L2224/80205	5	Ultrasonic bonding	<administrative transfer to H10W 80/335>
D	H01L2224/80206	6	Direction of oscillation	<administrative transfer to H10W 80/335>
D	H01L2224/80207	6	Thermosonic bonding	<administrative transfer to H10W 80/335>
D	H01L2224/80209	5	applying unidirectional static pressure	<administrative transfer to H10W 80/335>
D	H01L2224/80211	5	applying isostatic pressure, e.g. degassing using vacuum or a pressurised liquid	<administrative transfer to H10W 80/335>
D	H01L2224/80213	4	using a reflow oven	<administrative transfer to H10W 80/337>
D	H01L2224/80215	5	with a graded temperature profile	<administrative transfer to H10W 80/337>
D	H01L2224/8022	4	with energy being in the form of electromagnetic radiation	<administrative transfer to H10W 80/338>
D	H01L2224/80222	5	Induction heating, i.e. eddy currents	<administrative transfer to H10W 80/338>

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D	H01L2224/80224	5	using a laser	<administrative transfer to H10W 80/338>
D	H01L2224/8023	5	Polychromatic or infrared lamp heating	<administrative transfer to H10W 80/338>
D	H01L2224/80232	4	using an autocatalytic reaction, e.g. exothermic brazing	<administrative transfer to H10W 80/331>
D	H01L2224/80234	4	using means for applying energy being within the device, e.g. integrated heater	<administrative transfer to H10W 80/339>
D	H01L2224/80236	4	using electro-static corona discharge	<administrative transfer to H10W 80/331>
D	H01L2224/80237	4	using an electron beam	<administrative transfer to H10W 80/338>
D	H01L2224/80238	4	using electric resistance welding, i.e. ohmic heating	<administrative transfer to H10W 80/331>
D	H01L2224/8034	3	Bonding interfaces of the bonding area	<administrative transfer to H10W 72/90>
D	H01L2224/80345	4	Shape, e.g. interlocking features	<administrative transfer to H10W 72/931>
D	H01L2224/80355	4	having an external coating, e.g. protective bond-through coating	<administrative transfer to H10W 72/923>
D	H01L2224/80357	4	being flush with the surface	<administrative transfer to H10W 72/941>
D	H01L2224/80359	4	Material	<administrative transfer to H10W 72/951>
D	H01L2224/8036	3	Bonding interfaces of the semiconductor or solid state body	<administrative transfer to H10W 80/011>
D	H01L2224/80365	4	Shape, e.g. interlocking features	<administrative transfer to H10W 72/931>
D	H01L2224/80375	4	having an external coating, e.g. protective bond-through coating	<administrative transfer to H10W 80/023>
D	H01L2224/80379	4	Material	<administrative transfer to H10W 72/951>
D	H01L2224/8038	3	Bonding interfaces outside the semiconductor or solid-state body	<administrative transfer to H10W 80/011>
D	H01L2224/80385	4	Shape, e.g. interlocking features	<administrative transfer to H10W 72/931>
D	H01L2224/80395	4	having an external coating, e.g. protective bond-through coating	<administrative transfer to H10W 80/023>
D	H01L2224/80399	4	Material	<administrative transfer to H10W 72/951>
D	H01L2224/804	5	with a principal constituent of the material being a metal or a metalloid, e.g. boron [B], silicon [Si], germanium [Ge], arsenic [As], antimony [Sb], tellurium [Te] and polonium [Po], and alloys thereof	<administrative transfer to H10W 72/952>
D	H01L2224/80401	6	the principal constituent melting at a temperature of less than 400°C	<administrative transfer to H10W 72/952>

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D	H01L2224/80405	7	Gallium [Ga] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80409	7	Indium [In] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80411	7	Tin [Sn] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80413	7	Bismuth [Bi] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80414	7	Thallium [Tl] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80416	7	Lead [Pb] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80417	6	the principal constituent melting at a temperature of greater than or equal to 400°C and less than 950°C	<administrative transfer to H10W 72/952>
D	H01L2224/80418	7	Zinc [Zn] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/8042	7	Antimony [Sb] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80423	7	Magnesium [Mg] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80424	7	Aluminium [Al] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80438	6	the principal constituent melting at a temperature of greater than or equal to 950°C and less than 1550°C	<administrative transfer to H10W 72/952>
D	H01L2224/80439	7	Silver [Ag] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80444	7	Gold [Au] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80447	7	Copper [Cu] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80449	7	Manganese [Mn] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80455	7	Nickel [Ni] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80457	7	Cobalt [Co] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/8046	7	Iron [Fe] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80463	6	the principal constituent melting at a temperature of greater than 1550°C	<administrative transfer to H10W 72/952>
D	H01L2224/80464	7	Palladium [Pd] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80466	7	Titanium [Ti] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80469	7	Platinum [Pt] as principal constituent	<administrative transfer to H10W 72/952>

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D	H01L2224/8047	7	Zirconium [Zr] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80471	7	Chromium [Cr] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80472	7	Vanadium [V] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80473	7	Rhodium [Rh] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80476	7	Ruthenium [Ru] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80478	7	Iridium [Ir] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80479	7	Niobium [Nb] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/8048	7	Molybdenum [Mo] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80481	7	Tantalum [Ta] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80483	7	Rhenium [Re] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80484	7	Tungsten [W] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80486	5	with a principal constituent of the material being a non metallic, non metalloid inorganic material	<administrative transfer to H10W 72/953>
D	H01L2224/80487	6	Ceramics, e.g. crystalline carbides, nitrides or oxides	<administrative transfer to H10W 72/953>
D	H01L2224/80488	6	Glasses, e.g. amorphous oxides, nitrides or fluorides	<administrative transfer to H10W 72/953>
D	H01L2224/8049	5	with a principal constituent of the material being a polymer, e.g. polyester, phenolic based polymer, epoxy	<administrative transfer to H10W 72/953>
D	H01L2224/80491	6	The principal constituent being an elastomer, e.g. silicones, isoprene, neoprene	<administrative transfer to H10W 72/953>
D	H01L2224/80493	5	with a principal constituent of the material being a solid not provided for in groups H01L2224/804 - H01L2224/80491, e.g. allotropes of carbon, fullerene, graphite, carbon-nanotubes, diamond	<administrative transfer to H10W 72/953>
D	H01L2224/80494	5	with a principal constituent of the material being a liquid not provided for in groups H01L2224/804 - H01L2224/80491	<administrative transfer to H10W 72/953>
D	H01L2224/80495	5	with a principal constituent of the material being a gas not provided for in groups H01L2224/804 - H01L2224/80491	<administrative transfer to H10W 72/953>
D	H01L2224/80498	5	with a principal constituent of the material being a combination of two or more materials in the form of a matrix with a filler, i.e. being	<administrative transfer to H10W 72/951>

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			a hybrid material, e.g. segmented structures, foams	
D	H01L2224/80499	6	Material of the matrix	<administrative transfer to H10W 72/951>
D	H01L2224/805	7	with a principal constituent of the material being a metal or a metalloid, e.g. boron [B], silicon [Si], germanium [Ge], arsenic [As], antimony [Sb], tellurium [Te] and polonium [Po], and alloys thereof	<administrative transfer to H10W 72/952>
D	H01L2224/80501	8	the principal constituent melting at a temperature of less than 400°C	<administrative transfer to H10W 72/952>
D	H01L2224/80505	9	Gallium [Ga] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80509	9	Indium [In] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80511	9	Tin [Sn] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80513	9	Bismuth [Bi] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80514	9	Thallium [Tl] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80516	9	Lead [Pb] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80517	8	the principal constituent melting at a temperature of greater than or equal to 400°C and less than 950°C	<administrative transfer to H10W 72/952>
D	H01L2224/80518	9	Zinc [Zn] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/8052	9	Antimony [Sb] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80523	9	Magnesium [Mg] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80524	9	Aluminium [Al] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80538	8	the principal constituent melting at a temperature of greater than or equal to 950°C and less than 1550°C	<administrative transfer to H10W 72/952>
D	H01L2224/80539	9	Silver [Ag] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80544	9	Gold [Au] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80547	9	Copper [Cu] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80549	9	Manganese [Mn] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80555	9	Nickel [Ni] as principal constituent	<administrative transfer to H10W 72/952>

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D	H01L2224/80557	9	Cobalt [Co] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/8056	9	Iron [Fe] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80563	8	the principal constituent melting at a temperature of greater than 1550°C	<administrative transfer to H10W 72/952>
D	H01L2224/80564	9	Palladium [Pd] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80566	9	Titanium [Ti] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80569	9	Platinum [Pt] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/8057	9	Zirconium [Zr] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80571	9	Chromium [Cr] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80572	9	Vanadium [V] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80573	9	Rhodium [Rh] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80576	9	Ruthenium [Ru] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80578	9	Iridium [Ir] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80579	9	Niobium [Nb] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/8058	9	Molybdenum [Mo] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80581	9	Tantalum [Ta] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80583	9	Rhenium [Re] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80584	9	Tungsten [W] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80586	7	with a principal constituent of the material being a non metallic, non metalloid inorganic material	<administrative transfer to H10W 72/953>
D	H01L2224/80587	8	Ceramics, e.g. crystalline carbides, nitrides or oxides	<administrative transfer to H10W 72/953>
D	H01L2224/80588	8	Glasses, e.g. amorphous oxides, nitrides or fluorides	<administrative transfer to H10W 72/953>
D	H01L2224/8059	7	with a principal constituent of the material being a polymer, e.g. polyester, phenolic based polymer, epoxy	<administrative transfer to H10W 72/953>
D	H01L2224/80591	8	The principal constituent being an elastomer, e.g. silicones, isoprene, neoprene	<administrative transfer to H10W 72/953>
D	H01L2224/80593	7	with a principal constituent of the material being a solid not provided for in groups	<administrative transfer to H10W 72/953>

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			H01L2224/805 - H01L2224/80591, e.g. allotropes of carbon, fullerene, graphite, carbon-nanotubes, diamond	
D	H01L2224/80594	7	with a principal constituent of the material being a liquid not provided for in groups H01L2224/805 - H01L2224/80591	<administrative transfer to H10W 72/953>
D	H01L2224/80595	7	with a principal constituent of the material being a gas not provided for in groups H01L2224/805 - H01L2224/80591	<administrative transfer to H10W 72/953>
D	H01L2224/80598	6	Fillers	<administrative transfer to H10W 72/951>
D	H01L2224/80599	7	Base material	<administrative transfer to H10W 72/951>
D	H01L2224/806	8	with a principal constituent of the material being a metal or a metalloid, e.g. boron [B], silicon [Si], germanium [Ge], arsenic [As], antimony [Sb], tellurium [Te] and polonium [Po], and alloys thereof	<administrative transfer to H10W 72/952>
D	H01L2224/80601	9	the principal constituent melting at a temperature of less than 400°C	<administrative transfer to H10W 72/952>
D	H01L2224/80605	10	Gallium [Ga] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80609	10	Indium [In] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80611	10	Tin [Sn] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80613	10	Bismuth [Bi] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80614	10	Thallium [Tl] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80616	10	Lead [Pb] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80617	9	the principal constituent melting at a temperature of greater than or equal to 400°C and less than 950°C	<administrative transfer to H10W 72/952>
D	H01L2224/80618	10	Zinc [Zn] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/8062	10	Antimony [Sb] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80623	10	Magnesium [Mg] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80624	10	Aluminium [Al] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80638	9	the principal constituent melting at a temperature of greater than or equal to 950°C and less than 1550°C	<administrative transfer to H10W 72/952>
D	H01L2224/80639	10	Silver [Ag] as principal constituent	<administrative transfer to H10W 72/952>

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D	H01L2224/80644	10	Gold [Au] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80647	10	Copper [Cu] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80649	10	Manganese [Mn] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80655	10	Nickel [Ni] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80657	10	Cobalt [Co] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/8066	10	Iron [Fe] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80663	9	the principal constituent melting at a temperature of greater than 1550°C	<administrative transfer to H10W 72/952>
D	H01L2224/80664	10	Palladium [Pd] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80666	10	Titanium [Ti] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80669	10	Platinum [Pt] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/8067	10	Zirconium [Zr] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80671	10	Chromium [Cr] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80672	10	Vanadium [V] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80673	10	Rhodium [Rh] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80676	10	Ruthenium [Ru] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80678	10	Iridium [Ir] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80679	10	Niobium [Nb] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/8068	10	Molybdenum [Mo] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80681	10	Tantalum [Ta] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80683	10	Rhenium [Re] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80684	10	Tungsten [W] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80686	8	with a principal constituent of the material being a non metallic, non metalloid inorganic material	<administrative transfer to H10W 72/953>
D	H01L2224/80687	9	Ceramics, e.g. crystalline carbides, nitrides or oxides	<administrative transfer to H10W 72/953>

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D	H01L2224/80688	9	Glasses, e.g. amorphous oxides, nitrides or fluorides	<administrative transfer to H10W 72/953>
D	H01L2224/8069	8	with a principal constituent of the material being a polymer, e.g. polyester, phenolic based polymer, epoxy	<administrative transfer to H10W 72/953>
D	H01L2224/80691	9	The principal constituent being an elastomer, e.g. silicones, isoprene, neoprene	<administrative transfer to H10W 72/953>
D	H01L2224/80693	8	with a principal constituent of the material being a solid not provided for in groups H01L2224/806 - H01L2224/80691, e.g. allotropes of carbon, fullerene, graphite, carbon-nanotubes, diamond	<administrative transfer to H10W 72/953>
D	H01L2224/80694	8	with a principal constituent of the material being a liquid not provided for in groups H01L2224/806 - H01L2224/80691	<administrative transfer to H10W 72/953>
D	H01L2224/80695	8	with a principal constituent of the material being a gas not provided for in groups H01L2224/806 - H01L2224/80691	<administrative transfer to H10W 72/953>
D	H01L2224/80698	8	with a principal constituent of the material being a combination of two or more materials in the form of a matrix with a filler, i.e. being a hybrid material, e.g. segmented structures, foams	<administrative transfer to H10W 72/951>
D	H01L2224/80699	7	Coating material	<administrative transfer to H10W 72/951>
D	H01L2224/807	8	with a principal constituent of the material being a metal or a metalloid, e.g. boron [B], silicon [Si], germanium [Ge], arsenic [As], antimony [Sb], tellurium [Te] and polonium [Po], and alloys thereof	<administrative transfer to H10W 72/952>
D	H01L2224/80701	9	the principal constituent melting at a temperature of less than 400°C	<administrative transfer to H10W 72/952>
D	H01L2224/80705	10	Gallium [Ga] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80709	10	Indium [In] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80711	10	Tin [Sn] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80713	10	Bismuth [Bi] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80714	10	Thallium [Tl] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80716	10	Lead [Pb] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80717	9	the principal constituent melting at a temperature of greater than or equal to 400°C and less than 950°C	<administrative transfer to H10W 72/952>
D	H01L2224/80718	10	Zinc [Zn] as principal constituent	<administrative transfer to H10W 72/952>

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D	H01L2224/8072	10	Antimony [Sb] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80723	10	Magnesium [Mg] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80724	10	Aluminium [Al] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80738	9	the principal constituent melting at a temperature of greater than or equal to 950°C and less than 1550°C	<administrative transfer to H10W 72/952>
D	H01L2224/80739	10	Silver [Ag] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80744	10	Gold [Au] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80747	10	Copper [Cu] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80749	10	Manganese [Mn] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80755	10	Nickel [Ni] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80757	10	Cobalt [Co] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/8076	10	Iron [Fe] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80763	9	the principal constituent melting at a temperature of greater than 1550°C	<administrative transfer to H10W 72/952>
D	H01L2224/80764	10	Palladium [Pd] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80766	10	Titanium [Ti] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80769	10	Platinum [Pt] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/8077	10	Zirconium [Zr] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80771	10	Chromium [Cr] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80772	10	Vanadium [V] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80773	10	Rhodium [Rh] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80776	10	Ruthenium [Ru] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80778	10	Iridium [Ir] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80779	10	Niobium [Nb] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/8078	10	Molybdenum [Mo] as principal constituent	<administrative transfer to H10W 72/952>

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D	H01L2224/80781	10	Tantalum [Ta] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80783	10	Rhenium [Re] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80784	10	Tungsten [W] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/80786	8	with a principal constituent of the material being a non metallic, non metalloid inorganic material	<administrative transfer to H10W 72/953>
D	H01L2224/80787	9	Ceramics, e.g. crystalline carbides, nitrides or oxides	<administrative transfer to H10W 72/953>
D	H01L2224/80788	9	Glasses, e.g. amorphous oxides, nitrides or fluorides	<administrative transfer to H10W 72/953>
D	H01L2224/8079	8	with a principal constituent of the material being a polymer, e.g. polyester, phenolic based polymer, epoxy	<administrative transfer to H10W 72/953>
D	H01L2224/80791	9	The principal constituent being an elastomer, e.g. silicones, isoprene, neoprene	<administrative transfer to H10W 72/953>
D	H01L2224/80793	8	with a principal constituent of the material being a solid not provided for in groups H01L2224/807 - H01L2224/80791, e.g. allotropes of carbon, fullerene, graphite, carbon-nanotubes, diamond	<administrative transfer to H10W 72/953>
D	H01L2224/80794	8	with a principal constituent of the material being a liquid not provided for in groups H01L2224/807 - H01L2224/80791	<administrative transfer to H10W 72/953>
D	H01L2224/80795	8	with a principal constituent of the material being a gas not provided for in groups H01L2224/807 - H01L2224/80791	<administrative transfer to H10W 72/953>
D	H01L2224/80798	8	with a principal constituent of the material being a combination of two or more materials in the form of a matrix with a filler, i.e. being a hybrid material, e.g. segmented structures, foams	<administrative transfer to H10W 72/951>
D	H01L2224/80799	7	Shape or distribution of the fillers	<administrative transfer to H10W 72/951>
D	H01L2224/808	3	Bonding techniques	<administrative transfer to H10W 72/071>
D	H01L2224/80801	4	Soldering or alloying	<administrative transfer to H10W 72/07236>
D	H01L2224/80805	5	involving forming a eutectic alloy at the bonding interface	<administrative transfer to H10W 72/07236>
D	H01L2224/8081	5	involving forming an intermetallic compound at the bonding interface	<administrative transfer to H10W 72/07236>
D	H01L2224/80815	5	Reflow soldering	<administrative transfer to H10W 72/07236>
D	H01L2224/8082	5	Diffusion bonding	<administrative transfer to H10W 72/07236>

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D	H01L2224/80825	6	Solid-liquid interdiffusion	<administrative transfer to H10W 72/07236>
D	H01L2224/8083	6	Solid-solid interdiffusion	<administrative transfer to H10W 72/07236>
D	H01L2224/8084	4	Sintering	<administrative transfer to H10W 72/07231>
D	H01L2224/8085	4	using a polymer adhesive, e.g. an adhesive based on silicone, epoxy, polyimide, polyester	<administrative transfer to H10W 72/07337>
D	H01L2224/80855	5	Hardening the adhesive by curing, i.e. thermosetting	<administrative transfer to H10W 72/07338>
D	H01L2224/80856	6	Pre-cured adhesive, i.e. B-stage adhesive	<administrative transfer to H10W 72/07338>
D	H01L2224/80859	6	Localised curing of parts of the bonding area	<administrative transfer to H10W 72/07338>
D	H01L2224/80862	6	Heat curing	<administrative transfer to H10W 72/07338>
D	H01L2224/80865	6	Microwave curing	<administrative transfer to H10W 72/07338>
D	H01L2224/80868	6	Infrared [IR] curing	<administrative transfer to H10W 72/07338>
D	H01L2224/80871	6	Visible light curing	<administrative transfer to H10W 72/07338>
D	H01L2224/80874	6	Ultraviolet [UV] curing	<administrative transfer to H10W 72/07338>
D	H01L2224/80877	6	Moisture curing, i.e. curing by exposing to humidity, e.g. for silicones and polyurethanes	<administrative transfer to H10W 72/07338>
D	H01L2224/8088	5	Hardening the adhesive by cooling, e.g. for thermoplastics or hot-melt adhesives	<administrative transfer to H10W 72/07339>
D	H01L2224/80885	5	Combinations of two or more hardening methods provided for in at least two different groups from H01L2224/80855 - H01L2224/8088, e.g. for hybrid thermoplastic-thermosetting adhesives	<administrative transfer to H10W 72/07337>
D	H01L2224/8089	4	using an inorganic non metallic glass type adhesive, e.g. solder glass	<administrative transfer to H10W 72/073>
D	H01L2224/80893	4	Anodic bonding, i.e. bonding by applying a voltage across the interface in order to induce ions migration leading to an irreversible chemical bond	<administrative transfer to H10W 80/341>
D	H01L2224/80894	4	Direct bonding, i.e. joining surfaces by means of intermolecular attracting interactions at their interfaces, e.g. covalent bonds, van der Waals forces	<administrative transfer to H10W 80/301>
D	H01L2224/80895	5	between electrically conductive surfaces, e.g. copper-copper direct bonding, surface activated bonding	<administrative transfer to H10W 80/312>
D	H01L2224/80896	5	between electrically insulating surfaces, e.g. oxide or nitride layers	<administrative transfer to H10W 80/327>

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D	H01L2224/80897	4	Mechanical interlocking, e.g. anchoring, hook and loop-type fastening or the like	<administrative transfer to H10W 72/071>
D	H01L2224/80898	5	Press-fitting, i.e. pushing the parts together and fastening by friction, e.g. by compression of one part against the other	<administrative transfer to H10W 72/071>
D	H01L2224/80899	6	using resilient parts in the bonding area	<administrative transfer to H10W 72/071>
D	H01L2224/809	3	with the bonding area not providing any mechanical bonding	<administrative transfer to H10W 72/071>
D	H01L2224/80901	4	Pressing a bonding area against another bonding area by means of a further bonding area or connector	<administrative transfer to H10W 72/071>
D	H01L2224/80902	5	by means of a further bonding area	<administrative transfer to H10W 72/071>
D	H01L2224/80903	5	by means of a bump or layer connector	<administrative transfer to H10W 72/071>
D	H01L2224/80904	5	by means of an encapsulation layer or foil	<administrative transfer to H10W 72/071>
D	H01L2224/80905	3	Combinations of bonding methods provided for in at least two different groups from H01L2224/808 - H01L2224/80904	<administrative transfer to H10W 80/301>
D	H01L2224/80906	4	Specific sequence of method steps	<administrative transfer to H10W 80/301>
D	H01L2224/80907	4	Intermediate bonding, i.e. intermediate bonding step for temporarily bonding the semiconductor or solid-state body, followed by at least a further bonding step	<administrative transfer to H10W 80/301>
D	H01L2224/80908	3	involving monitoring, e.g. feedback loop	<administrative transfer to H10W 80/301>
D	H01L2224/80909	3	Post-treatment of the bonding area	<administrative transfer to H10W 72/019>
D	H01L2224/8091	4	Cleaning, e.g. oxide removal step, desmearing	<administrative transfer to H10W 72/01971>
D	H01L2224/80911	5	Chemical cleaning, e.g. etching, flux	<administrative transfer to H10W 72/01971>
D	H01L2224/80912	5	Mechanical cleaning, e.g. abrasion using hydro blasting, brushes, ultrasonic cleaning, dry ice blasting, gas-flow	<administrative transfer to H10W 72/01971>
D	H01L2224/80913	5	Plasma cleaning	<administrative transfer to H10W 72/01971>
D	H01L2224/80914	5	Thermal cleaning, e.g. using laser ablation or by electrostatic corona discharge	<administrative transfer to H10W 72/01971>
D	H01L2224/80919	5	Combinations of two or more cleaning methods provided for in at least two different groups from H01L2224/8091 - H01L2224/80914	<administrative transfer to H10W 72/01971>
D	H01L2224/8092	4	Applying permanent coating, e.g. protective coating	<administrative transfer to H10W 72/019>

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D	H01L2224/8093	4	Reshaping	<administrative transfer to H10W 72/01951>
D	H01L2224/80931	5	by chemical means, e.g. etching	<administrative transfer to H10W 72/01953>
D	H01L2224/80935	5	by heating means, e.g. reflowing	<administrative transfer to H10W 72/01951>
D	H01L2224/80937	6	using a polychromatic heating lamp	<administrative transfer to H10W 72/01951>
D	H01L2224/80939	6	using a laser	<administrative transfer to H10W 72/01951>
D	H01L2224/80941	6	Induction heating, i.e. eddy currents	<administrative transfer to H10W 72/01951>
D	H01L2224/80943	6	using a flame torch, e.g. hydrogen torch	<administrative transfer to H10W 72/01951>
D	H01L2224/80945	6	using a corona discharge, e.g. electronic flame off [EFO]	<administrative transfer to H10W 72/01951>
D	H01L2224/80947	5	by mechanical means, e.g. pull-and-cut, pressing, stamping	<administrative transfer to H10W 72/01951>
D	H01L2224/80948	4	Thermal treatments, e.g. annealing, controlled cooling	<administrative transfer to H10W 72/019>
D	H01L2224/80951	4	Forming additional members, e.g. for reinforcing	<administrative transfer to H10W 72/019>
D	H01L2224/80986	3	Specific sequence of steps, e.g. repetition of manufacturing steps, time sequence	<administrative transfer to H10W 72/019>
D	H01L2224/81	2	using a bump connector	<administrative transfer to H10W 72/072>
D	H01L2224/81001	3	involving a temporary auxiliary member not forming part of the bonding apparatus	<administrative transfer to H10W 72/07204>
D	H01L2224/81002	4	being a removable or sacrificial coating	<administrative transfer to H10W 72/07204>
D	H01L2224/81005	4	being a temporary or sacrificial substrate	<administrative transfer to H10W 72/07207>
D	H01L2224/81007	3	involving a permanent auxiliary member being left in the finished device, e.g. aids for holding or protecting the bump connector during or after the bonding process	<administrative transfer to H10W 72/07202>
D	H01L2224/81009	3	Pre-treatment of the bump connector or the bonding area	<administrative transfer to H10W 72/012>
D	H01L2224/8101	4	Cleaning the bump connector, e.g. oxide removal step, desmearing	<administrative transfer to H10W 72/01271 and H10W 72/072 simultaneously>
D	H01L2224/81011	5	Chemical cleaning, e.g. etching, flux	<administrative transfer to H10W 72/01271 and H10W 72/072 simultaneously>

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D	H01L2224/81012	5	Mechanical cleaning, e.g. abrasion using hydro blasting, brushes, ultrasonic cleaning, dry ice blasting, gas-flow	<administrative transfer to H10W 72/01271 and H10W 72/072 simultaneously>
D	H01L2224/81013	5	Plasma cleaning	<administrative transfer to H10W 72/01271 and H10W 72/072 simultaneously>
D	H01L2224/81014	5	Thermal cleaning, e.g. decomposition, sublimation	<administrative transfer to H10W 72/01271 and H10W 72/072 simultaneously>
D	H01L2224/81019	5	Combinations of two or more cleaning methods provided for in at least two different groups from H01L2224/8101 - H01L2224/81014	<administrative transfer to H10W 72/01271 and H10W 72/072 simultaneously>
D	H01L2224/8102	4	Applying permanent coating to the bump connector in the bonding apparatus, e.g. in-situ coating	<administrative transfer to H10W 72/01215 and H10W 72/072 simultaneously>
D	H01L2224/81022	4	Cleaning the bonding area, e.g. oxide removal step, desmearing	<administrative transfer to H10W 72/07211>
D	H01L2224/81024	4	Applying flux to the bonding area	<administrative transfer to H10W 72/07211>
D	H01L2224/81026	4	Applying a precursor material to the bonding area	<administrative transfer to H10W 72/07211>
D	H01L2224/8103	4	Reshaping the bump connector in the bonding apparatus, e.g. flattening the bump connector	<administrative transfer to H10W 72/01251 and H10W 72/072 simultaneously>
D	H01L2224/81031	5	by chemical means, e.g. etching, anodisation	<administrative transfer to H10W 72/01253 and H10W 72/072 simultaneously>
D	H01L2224/81035	5	by heating means	<administrative transfer to H10W 72/01257 and H10W 72/072 simultaneously>
D	H01L2224/81037	6	using a polychromatic heating lamp	<administrative transfer to H10W 72/01257 and H10W 72/072 simultaneously>
D	H01L2224/81039	6	using a laser	<administrative transfer to H10W 72/01257 and H10W 72/072 simultaneously>
D	H01L2224/81041	6	Induction heating, i.e. eddy currents	<administrative transfer to H10W 72/01257 and H10W 72/072 simultaneously>

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D	H01L2224/81047	5	by mechanical means, e.g. severing, pressing, stamping	<administrative transfer to H10W 72/01257 and H10W 72/072 simultaneously>
D	H01L2224/81048	4	Thermal treatments, e.g. annealing, controlled pre-heating or pre-cooling	<administrative transfer to H10W 72/012 and H10W 72/072 simultaneously>
D	H01L2224/81051	4	Forming additional members	<administrative transfer to H10W 72/012 and H10W 72/072 simultaneously>
D	H01L2224/81052	3	Detaching bump connectors, e.g. after testing	<administrative transfer to H10W 72/072>
D	H01L2224/81053	3	Bonding environment	<administrative transfer to H10W 72/016>
D	H01L2224/81054	4	Composition of the atmosphere	<administrative transfer to H10W 72/016>
D	H01L2224/81055	5	being oxidating	<administrative transfer to H10W 72/016>
D	H01L2224/81065	5	being reducing	<administrative transfer to H10W 72/016>
D	H01L2224/81075	5	being inert	<administrative transfer to H10W 72/016>
D	H01L2224/81085	4	being a liquid, e.g. for fluidic self-assembly	<administrative transfer to H10W 72/016>
D	H01L2224/8109	4	Vacuum	<administrative transfer to H10W 72/016>
D	H01L2224/81091	4	Under pressure	<administrative transfer to H10W 72/016>
D	H01L2224/81092	5	Atmospheric pressure	<administrative transfer to H10W 72/016>
D	H01L2224/81093	5	Transient conditions, e.g. gas-flow	<administrative transfer to H10W 72/016>
D	H01L2224/81095	4	Temperature settings	<administrative transfer to H10W 72/016>
D	H01L2224/81096	5	Transient conditions	<administrative transfer to H10W 72/016>
D	H01L2224/81097	6	Heating	<administrative transfer to H10W 72/016>
D	H01L2224/81098	6	Cooling	<administrative transfer to H10W 72/016>
D	H01L2224/81099	5	Ambient temperature	<administrative transfer to H10W 72/016>
D	H01L2224/811	3	the bump connector being supplied to the parts to be connected in the bonding apparatus	<administrative transfer to H10W 72/01212 and H10W 72/072 simultaneously>

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D	H01L2224/81101	4	as prepeg comprising a bump connector, e.g. provided in an insulating plate member	<administrative transfer to H10W 72/01212 and H10W 72/072 simultaneously>
D	H01L2224/8111	3	involving protection against electrical discharge, e.g. removing electrostatic charge	<administrative transfer to H10W 72/072>
D	H01L2224/8112	3	Aligning	<administrative transfer to H10W 72/07221>
D	H01L2224/81121	4	Active alignment, i.e. by apparatus steering, e.g. optical alignment using marks or sensors	<administrative transfer to H10W 72/07223>
D	H01L2224/81122	5	by detecting inherent features of, or outside, the semiconductor or solid-state body	<administrative transfer to H10W 72/07223>
D	H01L2224/81123	6	Shape or position of the body	<administrative transfer to H10W 72/07223>
D	H01L2224/81125	6	Bonding areas on the body	<administrative transfer to H10W 72/07223>
D	H01L2224/81127	6	Bonding areas outside the body	<administrative transfer to H10W 72/07223>
D	H01L2224/81129	6	Shape or position of the other item	<administrative transfer to H10W 72/07223>
D	H01L2224/8113	5	using marks formed on the semiconductor or solid-state body	<administrative transfer to H10W 72/07223>
D	H01L2224/81132	5	using marks formed outside the semiconductor or solid-state body, i.e. "off-chip"	<administrative transfer to H10W 72/07223>
D	H01L2224/81136	4	involving guiding structures, e.g. spacers or supporting members	<administrative transfer to H10W 72/07227>
D	H01L2224/81138	5	the guiding structures being at least partially left in the finished device	<administrative transfer to H10W 72/07227>
D	H01L2224/81139	6	Guiding structures on the body	<administrative transfer to H10W 72/07227>
D	H01L2224/8114	6	Guiding structures outside the body	<administrative transfer to H10W 72/07227>
D	H01L2224/81141	6	Guiding structures both on and outside the body	<administrative transfer to H10W 72/07227>
D	H01L2224/81143	4	Passive alignment, i.e. self alignment, e.g. using surface energy, chemical reactions, thermal equilibrium	<administrative transfer to H10W 72/07221>
D	H01L2224/81148	4	involving movement of a part of the bonding apparatus	<administrative transfer to H10W 72/072>
D	H01L2224/81149	5	being the lower part of the bonding apparatus, i.e. holding means for the bodies to be connected, e.g. XY table	<administrative transfer to H10W 72/072>
D	H01L2224/8115	6	Rotational movements	<administrative transfer to H10W 72/072>
D	H01L2224/8116	6	Translational movements	<administrative transfer to H10W 72/072>

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D	H01L2224/81169	5	being the upper part of the bonding apparatus, i.e. bonding head	<administrative transfer to H10W 72/072>
D	H01L2224/8117	6	Rotational movements	<administrative transfer to H10W 72/072>
D	H01L2224/8118	6	Translational movements	<administrative transfer to H10W 72/072>
D	H01L2224/8119	3	Arrangement of the bump connectors prior to mounting	<administrative transfer to H10W 72/241 and H10W 72/072 simultaneously>
D	H01L2224/81191	4	wherein the bump connectors are disposed only on the semiconductor or solid-state body	<administrative transfer to H10W 72/241 and H10W 72/072 simultaneously>
D	H01L2224/81192	4	wherein the bump connectors are disposed only on another item or body to be connected to the semiconductor or solid-state body	<administrative transfer to H10W 72/241 and H10W 72/072 simultaneously>
D	H01L2224/81193	4	wherein the bump connectors are disposed on both the semiconductor or solid-state body and another item or body to be connected to the semiconductor or solid-state body	<administrative transfer to H10W 72/241 and H10W 72/072 simultaneously>
D	H01L2224/81194	4	Lateral distribution of the bump connectors	<administrative transfer to H10W 72/248 and H10W 72/072 simultaneously>
D	H01L2224/812	3	Applying energy for connecting	<administrative transfer to H10W 72/07231>
D	H01L2224/81201	4	Compression bonding	<administrative transfer to H10W 72/07232>
D	H01L2224/81203	5	Thermocompression bonding, e.g. diffusion bonding, pressure joining, thermocompression welding or solid-state welding	<administrative transfer to H10W 72/07232>
D	H01L2224/81204	6	with a graded temperature profile	<administrative transfer to H10W 72/07232>
D	H01L2224/81205	5	Ultrasonic bonding	<administrative transfer to H10W 72/07233>
D	H01L2224/81206	6	Direction of oscillation	<administrative transfer to H10W 72/07233>
D	H01L2224/81207	6	Thermosonic bonding	<administrative transfer to H10W 72/07233>
D	H01L2224/81208	5	applying unidirectional static pressure	<administrative transfer to H10W 72/07232>
D	H01L2224/81209	5	applying isostatic pressure, e.g. degassing using vacuum or a pressurised liquid	<administrative transfer to H10W 72/07232>
D	H01L2224/8121	4	using a reflow oven	<administrative transfer to H10W 72/07234>

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D	H01L2224/81211	5	with a graded temperature profile	<administrative transfer to H10W 72/07234>
D	H01L2224/8122	4	with energy being in the form of electromagnetic radiation	<administrative transfer to H10W 72/07235>
D	H01L2224/81222	5	Induction heating, i.e. eddy currents	<administrative transfer to H10W 72/07235>
D	H01L2224/81224	5	using a laser	<administrative transfer to H10W 72/07235>
D	H01L2224/8123	5	Polychromatic or infrared lamp heating	<administrative transfer to H10W 72/07235>
D	H01L2224/81232	4	using an autocatalytic reaction, e.g. exothermic brazing	<administrative transfer to H10W 72/072>
D	H01L2224/81234	4	using means for applying energy being within the device, e.g. integrated heater	<administrative transfer to H10W 72/072>
D	H01L2224/81236	4	using electro-static corona discharge	<administrative transfer to H10W 72/072>
D	H01L2224/81237	4	using an electron beam	<administrative transfer to H10W 72/072>
D	H01L2224/81238	4	using electric resistance welding, i.e. ohmic heating	<administrative transfer to H10W 72/072>
D	H01L2224/8134	3	Bonding interfaces of the bump connector	<administrative transfer to H10W 72/072>
D	H01L2224/81345	4	Shape, e.g. interlocking features	<administrative transfer to H10W 72/072 and H10W 72/07253 simultaneously>
D	H01L2224/81355	4	having an external coating, e.g. protective bond-through coating	<administrative transfer to H10W 72/072 and H10W 72/222 simultaneously>
D	H01L2224/81359	4	Material	<administrative transfer to H10W 72/072, H10W 72/251 and H10W 72/2528 simultaneously>
D	H01L2224/8136	3	Bonding interfaces of the semiconductor or solid state body	<administrative transfer to H10W 72/072>
D	H01L2224/81365	4	Shape, e.g. interlocking features	<administrative transfer to H10W 72/072>
D	H01L2224/81375	4	having an external coating, e.g. protective bond-through coating	<administrative transfer to H10W 72/072>
D	H01L2224/81379	4	Material	<administrative transfer to H10W 72/072>
D	H01L2224/8138	3	Bonding interfaces outside the semiconductor or solid-state body	<administrative transfer to H10W 72/072>
D	H01L2224/81385	4	Shape, e.g. interlocking features	<administrative transfer to H10W 72/072>

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D	H01L2224/81395	4	having an external coating, e.g. protective bond-through coating	<administrative transfer to H10W 72/072>
D	H01L2224/81399	4	Material	<administrative transfer to H10W 72/072>
D	H01L2224/814	5	with a principal constituent of the material being a metal or a metalloid, e.g. boron [B], silicon [Si], germanium [Ge], arsenic [As], antimony [Sb], tellurium [Te] and polonium [Po], and alloys thereof	<administrative transfer to H10W 72/072>
D	H01L2224/81401	6	the principal constituent melting at a temperature of less than 400°C	<administrative transfer to H10W 72/072>
D	H01L2224/81405	7	Gallium [Ga] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81409	7	Indium [In] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81411	7	Tin [Sn] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81413	7	Bismuth [Bi] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81414	7	Thallium [Tl] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81416	7	Lead [Pb] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81417	6	the principal constituent melting at a temperature of greater than or equal to 400°C and less than 950°C	<administrative transfer to H10W 72/072>
D	H01L2224/81418	7	Zinc [Zn] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/8142	7	Antimony [Sb] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81423	7	Magnesium [Mg] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81424	7	Aluminium [Al] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81438	6	the principal constituent melting at a temperature of greater than or equal to 950°C and less than 1550°C	<administrative transfer to H10W 72/072>
D	H01L2224/81439	7	Silver [Ag] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81444	7	Gold [Au] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81447	7	Copper [Cu] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81449	7	Manganese [Mn] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81455	7	Nickel [Ni] as principal constituent	<administrative transfer to H10W 72/072>

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D	H01L2224/81457	7	Cobalt [Co] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/8146	7	Iron [Fe] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81463	6	the principal constituent melting at a temperature of greater than 1550°C	<administrative transfer to H10W 72/072>
D	H01L2224/81464	7	Palladium [Pd] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81466	7	Titanium [Ti] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81469	7	Platinum [Pt] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/8147	7	Zirconium [Zr] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81471	7	Chromium [Cr] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81472	7	Vanadium [V] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81473	7	Rhodium [Rh] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81476	7	Ruthenium [Ru] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81478	7	Iridium [Ir] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81479	7	Niobium [Nb] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/8148	7	Molybdenum [Mo] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81481	7	Tantalum [Ta] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81483	7	Rhenium [Re] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81484	7	Tungsten [W] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81486	5	with a principal constituent of the material being a non metallic, non metalloid inorganic material	<administrative transfer to H10W 72/072>
D	H01L2224/81487	6	Ceramics, e.g. crystalline carbides, nitrides or oxides	<administrative transfer to H10W 72/072>
D	H01L2224/81488	6	Glasses, e.g. amorphous oxides, nitrides or fluorides	<administrative transfer to H10W 72/072>
D	H01L2224/8149	5	with a principal constituent of the material being a polymer, e.g. polyester, phenolic based polymer, epoxy	<administrative transfer to H10W 72/072>
D	H01L2224/81491	6	The principal constituent being an elastomer, e.g. silicones, isoprene, neoprene	<administrative transfer to H10W 72/072>
D	H01L2224/81493	5	with a principal constituent of the material being a solid not provided for in groups	<administrative transfer to H10W 72/072>

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			H01L2224/814 - H01L2224/81491, e.g. allotropes of carbon, fullerene, graphite, carbon-nanotubes, diamond	
D	H01L2224/81494	5	with a principal constituent of the material being a liquid not provided for in groups H01L2224/814 - H01L2224/81491	<administrative transfer to H10W 72/072>
D	H01L2224/81495	5	with a principal constituent of the material being a gas not provided for in groups H01L2224/814 - H01L2224/81491	<administrative transfer to H10W 72/072>
D	H01L2224/81498	5	with a principal constituent of the material being a combination of two or more materials in the form of a matrix with a filler, i.e. being a hybrid material, e.g. segmented structures, foams	<administrative transfer to H10W 72/072>
D	H01L2224/81499	6	Material of the matrix	<administrative transfer to H10W 72/072>
D	H01L2224/815	7	with a principal constituent of the material being a metal or a metalloid, e.g. boron [B], silicon [Si], germanium [Ge], arsenic [As], antimony [Sb], tellurium [Te] and polonium [Po], and alloys thereof	<administrative transfer to H10W 72/072>
D	H01L2224/81501	8	the principal constituent melting at a temperature of less than 400°C	<administrative transfer to H10W 72/072>
D	H01L2224/81505	9	Gallium [Ga] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81509	9	Indium [In] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81511	9	Tin [Sn] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81513	9	Bismuth [Bi] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81514	9	Thallium [Tl] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81516	9	Lead [Pb] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81517	8	the principal constituent melting at a temperature of greater than or equal to 400°C and less than 950°C	<administrative transfer to H10W 72/072>
D	H01L2224/81518	9	Zinc [Zn] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/8152	9	Antimony [Sb] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81523	9	Magnesium [Mg] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81524	9	Aluminium [Al] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81538	8	the principal constituent melting at a temperature of greater than or equal to 950°C and less than 1550°C	<administrative transfer to H10W 72/072>

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D	H01L2224/81539	9	Silver [Ag] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81544	9	Gold [Au] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81547	9	Copper [Cu] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81549	9	Manganese [Mn] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81555	9	Nickel [Ni] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81557	9	Cobalt [Co] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/8156	9	Iron [Fe] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81563	8	the principal constituent melting at a temperature of greater than 1550°C	<administrative transfer to H10W 72/072>
D	H01L2224/81564	9	Palladium [Pd] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81566	9	Titanium [Ti] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81569	9	Platinum [Pt] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/8157	9	Zirconium [Zr] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81571	9	Chromium [Cr] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81572	9	Vanadium [V] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81573	9	Rhodium [Rh] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81576	9	Ruthenium [Ru] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81578	9	Iridium [Ir] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81579	9	Niobium [Nb] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/8158	9	Molybdenum [Mo] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81581	9	Tantalum [Ta] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81583	9	Rhenium [Re] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81584	9	Tungsten [W] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81586	7	with a principal constituent of the material being a non metallic, non metalloid inorganic material	<administrative transfer to H10W 72/072>

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D	H01L2224/81587	8	Ceramics, e.g. crystalline carbides, nitrides or oxides	<administrative transfer to H10W 72/072>
D	H01L2224/81588	8	Glasses, e.g. amorphous oxides, nitrides or fluorides	<administrative transfer to H10W 72/072>
D	H01L2224/8159	7	with a principal constituent of the material being a polymer, e.g. polyester, phenolic based polymer, epoxy	<administrative transfer to H10W 72/072>
D	H01L2224/81591	8	The principal constituent being an elastomer, e.g. silicones, isoprene, neoprene	<administrative transfer to H10W 72/072>
D	H01L2224/81593	7	with a principal constituent of the material being a solid not provided for in groups H01L2224/815 - H01L2224/81591, e.g. allotropes of carbon, fullerene, graphite, carbon-nanotubes, diamond	<administrative transfer to H10W 72/072>
D	H01L2224/81594	7	with a principal constituent of the material being a liquid not provided for in groups H01L2224/815 - H01L2224/81591	<administrative transfer to H10W 72/072>
D	H01L2224/81595	7	with a principal constituent of the material being a gas not provided for in groups H01L2224/815 - H01L2224/81591	<administrative transfer to H10W 72/072>
D	H01L2224/81598	6	Fillers	<administrative transfer to H10W 72/072>
D	H01L2224/81599	7	Base material	<administrative transfer to H10W 72/072>
D	H01L2224/816	8	with a principal constituent of the material being a metal or a metalloid, e.g. boron [B], silicon [Si], germanium [Ge], arsenic [As], antimony [Sb], tellurium [Te] and polonium [Po], and alloys thereof	<administrative transfer to H10W 72/072>
D	H01L2224/81601	9	the principal constituent melting at a temperature of less than 400°C	<administrative transfer to H10W 72/072>
D	H01L2224/81605	10	Gallium [Ga] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81609	10	Indium [In] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81611	10	Tin [Sn] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81613	10	Bismuth [Bi] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81614	10	Thallium [Tl] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81616	10	Lead [Pb] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81617	9	the principal constituent melting at a temperature of greater than or equal to 400°C and less than 950°C	<administrative transfer to H10W 72/072>
D	H01L2224/81618	10	Zinc [Zn] as principal constituent	<administrative transfer to H10W 72/072>

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D	H01L2224/8162	10	Antimony [Sb] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81623	10	Magnesium [Mg] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81624	10	Aluminium [Al] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81638	9	the principal constituent melting at a temperature of greater than or equal to 950°C and less than 1550°C	<administrative transfer to H10W 72/072>
D	H01L2224/81639	10	Silver [Ag] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81644	10	Gold [Au] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81647	10	Copper [Cu] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81649	10	Manganese [Mn] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81655	10	Nickel [Ni] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81657	10	Cobalt [Co] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/8166	10	Iron [Fe] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81663	9	the principal constituent melting at a temperature of greater than 1550°C	<administrative transfer to H10W 72/072>
D	H01L2224/81664	10	Palladium [Pd] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81666	10	Titanium [Ti] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81669	10	Platinum [Pt] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/8167	10	Zirconium [Zr] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81671	10	Chromium [Cr] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81672	10	Vanadium [V] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81673	10	Rhodium [Rh] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81676	10	Ruthenium [Ru] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81678	10	Iridium [Ir] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81679	10	Niobium [Nb] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/8168	10	Molybdenum [Mo] as principal constituent	<administrative transfer to H10W 72/072>

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D	H01L2224/81681	10	Tantalum [Ta] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81683	10	Rhenium [Re] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81684	10	Tungsten [W] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81686	8	with a principal constituent of the material being a non metallic, non metalloid inorganic material	<administrative transfer to H10W 72/072>
D	H01L2224/81687	9	Ceramics, e.g. crystalline carbides, nitrides or oxides	<administrative transfer to H10W 72/072>
D	H01L2224/81688	9	Glasses, e.g. amorphous oxides, nitrides or fluorides	<administrative transfer to H10W 72/072>
D	H01L2224/8169	8	with a principal constituent of the material being a polymer, e.g. polyester, phenolic based polymer, epoxy	<administrative transfer to H10W 72/072>
D	H01L2224/81691	9	The principal constituent being an elastomer, e.g. silicones, isoprene, neoprene	<administrative transfer to H10W 72/072>
D	H01L2224/81693	8	with a principal constituent of the material being a solid not provided for in groups H01L2224/816 - H01L2224/81691, e.g. allotropes of carbon, fullerene, graphite, carbon-nanotubes, diamond	<administrative transfer to H10W 72/072>
D	H01L2224/81694	8	with a principal constituent of the material being a liquid not provided for in groups H01L2224/816 - H01L2224/81691	<administrative transfer to H10W 72/072>
D	H01L2224/81695	8	with a principal constituent of the material being a gas not provided for in groups H01L2224/816 - H01L2224/81691	<administrative transfer to H10W 72/072>
D	H01L2224/81698	8	with a principal constituent of the material being a combination of two or more materials in the form of a matrix with a filler, i.e. being a hybrid material, e.g. segmented structures, foams	<administrative transfer to H10W 72/072>
D	H01L2224/81699	7	Coating material	<administrative transfer to H10W 72/072>
D	H01L2224/817	8	with a principal constituent of the material being a metal or a metalloid, e.g. boron [B], silicon [Si], germanium [Ge], arsenic [As], antimony [Sb], tellurium [Te] and polonium [Po], and alloys thereof	<administrative transfer to H10W 72/072>
D	H01L2224/81701	9	the principal constituent melting at a temperature of less than 400°C	<administrative transfer to H10W 72/072>
D	H01L2224/81705	10	Gallium [Ga] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81709	10	Indium [In] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81711	10	Tin [Sn] as principal constituent	<administrative transfer to H10W 72/072>

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D	H01L2224/81713	10	Bismuth [Bi] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81714	10	Thallium [Tl] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81716	10	Lead [Pb] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81717	9	the principal constituent melting at a temperature of greater than or equal to 400°C and less than 950°C	<administrative transfer to H10W 72/072>
D	H01L2224/81718	10	Zinc [Zn] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/8172	10	Antimony [Sb] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81723	10	Magnesium [Mg] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81724	10	Aluminium [Al] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81738	9	the principal constituent melting at a temperature of greater than or equal to 950°C and less than 1550°C	<administrative transfer to H10W 72/072>
D	H01L2224/81739	10	Silver [Ag] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81744	10	Gold [Au] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81747	10	Copper [Cu] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81749	10	Manganese [Mn] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81755	10	Nickel [Ni] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81757	10	Cobalt [Co] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/8176	10	Iron [Fe] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81763	9	the principal constituent melting at a temperature of greater than 1550°C	<administrative transfer to H10W 72/072>
D	H01L2224/81764	10	Palladium [Pd] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81766	10	Titanium [Ti] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81769	10	Platinum [Pt] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/8177	10	Zirconium [Zr] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81771	10	Chromium [Cr] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81772	10	Vanadium [V] as principal constituent	<administrative transfer to H10W 72/072>

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D	H01L2224/81773	10	Rhodium [Rh] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81776	10	Ruthenium [Ru] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81778	10	Iridium [Ir] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81779	10	Niobium [Nb] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/8178	10	Molybdenum [Mo] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81781	10	Tantalum [Ta] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81783	10	Rhenium [Re] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81784	10	Tungsten [W] as principal constituent	<administrative transfer to H10W 72/072>
D	H01L2224/81786	8	with a principal constituent of the material being a non metallic, non metalloid inorganic material	<administrative transfer to H10W 72/072>
D	H01L2224/81787	9	Ceramics, e.g. crystalline carbides, nitrides or oxides	<administrative transfer to H10W 72/072>
D	H01L2224/81788	9	Glasses, e.g. amorphous oxides, nitrides or fluorides	<administrative transfer to H10W 72/072>
D	H01L2224/8179	8	with a principal constituent of the material being a polymer, e.g. polyester, phenolic based polymer, epoxy	<administrative transfer to H10W 72/072>
D	H01L2224/81791	9	The principal constituent being an elastomer, e.g. silicones, isoprene, neoprene	<administrative transfer to H10W 72/072>
D	H01L2224/81793	8	with a principal constituent of the material being a solid not provided for in groups H01L2224/817 - H01L2224/81791, e.g. allotropes of carbon, fullerene, graphite, carbon-nanotubes, diamond	<administrative transfer to H10W 72/072>
D	H01L2224/81794	8	with a principal constituent of the material being a liquid not provided for in groups H01L2224/817 - H01L2224/81791	<administrative transfer to H10W 72/072>
D	H01L2224/81795	8	with a principal constituent of the material being a gas not provided for in groups H01L2224/817 - H01L2224/81791	<administrative transfer to H10W 72/072>
D	H01L2224/81798	8	with a principal constituent of the material being a combination of two or more materials in the form of a matrix with a filler, i.e. being a hybrid material, e.g. segmented structures, foams	<administrative transfer to H10W 72/072>
D	H01L2224/81799	7	Shape or distribution of the fillers	<administrative transfer to H10W 72/072>
D	H01L2224/818	3	Bonding techniques	<administrative transfer to H10W 72/07231>

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D	H01L2224/81801	4	Soldering or alloying	<administrative transfer to H10W 72/07236>
D	H01L2224/81805	5	involving forming a eutectic alloy at the bonding interface	<administrative transfer to H10W 72/07236>
D	H01L2224/8181	5	involving forming an intermetallic compound at the bonding interface	<administrative transfer to H10W 72/07236>
D	H01L2224/81815	5	Reflow soldering	<administrative transfer to H10W 72/07236>
D	H01L2224/8182	5	Diffusion bonding	<administrative transfer to H10W 72/07236>
D	H01L2224/81825	6	Solid-liquid interdiffusion	<administrative transfer to H10W 72/07236>
D	H01L2224/8183	6	Solid-solid interdiffusion	<administrative transfer to H10W 72/07236>
D	H01L2224/8184	4	Sintering	<administrative transfer to H10W 72/072>
D	H01L2224/8185	4	using a polymer adhesive, e.g. an adhesive based on silicone, epoxy, polyimide, polyester	<administrative transfer to H10W 72/07237>
D	H01L2224/81855	5	Hardening the adhesive by curing, i.e. thermosetting	<administrative transfer to H10W 72/07237>
D	H01L2224/81856	6	Pre-cured adhesive, i.e. B-stage adhesive	<administrative transfer to H10W 72/07237>
D	H01L2224/81859	6	Localised curing of parts of the bump connector	<administrative transfer to H10W 72/07237>
D	H01L2224/81862	6	Heat curing	<administrative transfer to H10W 72/07237>
D	H01L2224/81865	6	Microwave curing	<administrative transfer to H10W 72/07237>
D	H01L2224/81868	6	Infrared [IR] curing	<administrative transfer to H10W 72/07237>
D	H01L2224/81871	6	Visible light curing	<administrative transfer to H10W 72/07237>
D	H01L2224/81874	6	Ultraviolet [UV] curing	<administrative transfer to H10W 72/07237>
D	H01L2224/81877	6	Moisture curing, i.e. curing by exposing to humidity, e.g. for silicones and polyurethanes	<administrative transfer to H10W 72/07237>
D	H01L2224/8188	5	Hardening the adhesive by cooling, e.g. for thermoplastics or hot-melt adhesives	<administrative transfer to H10W 72/07237>
D	H01L2224/81885	5	Combinations of two or more hardening methods provided for in at least two different groups from H01L2224/81855 - H01L2224/8188, e.g. for hybrid thermoplastic-thermosetting adhesives	<administrative transfer to H10W 72/07237>
D	H01L2224/8189	4	using an inorganic non metallic glass type adhesive, e.g. solder glass	<administrative transfer to H10W 72/07231>
D	H01L2224/81893	4	Anodic bonding, i.e. bonding by applying a voltage across the interface in order to induce	<administrative transfer to H10W 72/07231>

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			ions migration leading to an irreversible chemical bond	
D	H01L2224/81894	4	Direct bonding, i.e. joining surfaces by means of intermolecular attracting interactions at their interfaces, e.g. covalent bonds, van der Waals forces	<administrative transfer to H10W 80/301>
D	H01L2224/81895	5	between electrically conductive surfaces, e.g. copper-copper direct bonding, surface activated bonding	<administrative transfer to H10W 80/314>
D	H01L2224/81896	5	between electrically insulating surfaces, e.g. oxide or nitride layers	<administrative transfer to H10W 80/327>
D	H01L2224/81897	4	Mechanical interlocking, e.g. anchoring, hook and loop-type fastening or the like	<administrative transfer to H10W 72/07231>
D	H01L2224/81898	5	Press-fitting, i.e. pushing the parts together and fastening by friction, e.g. by compression of one part against the other	<administrative transfer to H10W 72/07231>
D	H01L2224/81899	6	using resilient parts in the bump connector or in the bonding area	<administrative transfer to H10W 72/07231>
D	H01L2224/819	3	with the bump connector not providing any mechanical bonding	<administrative transfer to H10W 72/261>
D	H01L2224/81901	4	Pressing the bump connector against the bonding areas by means of another connector	<administrative transfer to H10W 72/261>
D	H01L2224/81902	5	by means of another bump connector	<administrative transfer to H10W 72/261>
D	H01L2224/81903	5	by means of a layer connector	<administrative transfer to H10W 72/261>
D	H01L2224/81904	5	by means of an encapsulation layer or foil	<administrative transfer to H10W 72/261>
D	H01L2224/81905	3	Combinations of bonding methods provided for in at least two different groups from H01L2224/818 - H01L2224/81904	<administrative transfer to H10W 72/07231>
D	H01L2224/81906	4	Specific sequence of method steps	<administrative transfer to H10W 72/07231>
D	H01L2224/81907	4	Intermediate bonding, i.e. intermediate bonding step for temporarily bonding the semiconductor or solid-state body, followed by at least a further bonding step	<administrative transfer to H10W 72/07231>
D	H01L2224/81908	3	involving monitoring, e.g. feedback loop	<administrative transfer to H10W 72/07231>
D	H01L2224/81909	3	Post-treatment of the bump connector or bonding area	<administrative transfer to H10W 72/012 and H10W 72/072 simultaneously>
D	H01L2224/8191	4	Cleaning, e.g. oxide removal step, desmearing	<administrative transfer to H10W 72/01271 and H10W 72/072 simultaneously>
D	H01L2224/81911	5	Chemical cleaning, e.g. etching, flux	<administrative transfer to H10W 72/01271 and

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				H10W 72/072 simultaneously>
D	H01L2224/81912	5	Mechanical cleaning, e.g. abrasion using hydro blasting, brushes, ultrasonic cleaning, dry ice blasting, gas-flow	<administrative transfer to H10W 72/01271 and H10W 72/072 simultaneously>
D	H01L2224/81913	5	Plasma cleaning	<administrative transfer to H10W 72/01271 and H10W 72/072 simultaneously>
D	H01L2224/81914	5	Thermal cleaning, e.g. using laser ablation or by electrostatic corona discharge	<administrative transfer to H10W 72/01271 and H10W 72/072 simultaneously>
D	H01L2224/81919	5	Combinations of two or more cleaning methods provided for in at least two different groups from H01L2224/8191 - H01L2224/81914	<administrative transfer to H10W 72/01271 and H10W 72/072 simultaneously>
D	H01L2224/8192	4	Applying permanent coating, e.g. protective coating	<administrative transfer to H10W 72/01215 and H10W 72/072 simultaneously>
D	H01L2224/8193	4	Reshaping	<administrative transfer to H10W 72/01251 and H10W 72/072 simultaneously>
D	H01L2224/81931	5	by chemical means, e.g. etching	<administrative transfer to H10W 72/01253 and H10W 72/072 simultaneously>
D	H01L2224/81935	5	by heating means, e.g. reflowing	<administrative transfer to H10W 72/01257 and H10W 72/072 simultaneously>
D	H01L2224/81937	6	using a polychromatic heating lamp	<administrative transfer to H10W 72/01251 and H10W 72/072 simultaneously>
D	H01L2224/81939	6	using a laser	<administrative transfer to H10W 72/01251 and H10W 72/072 simultaneously>
D	H01L2224/81941	6	Induction heating, i.e. eddy currents	<administrative transfer to H10W 72/01251 and H10W 72/072 simultaneously>
D	H01L2224/81943	6	using a flame torch, e.g. hydrogen torch	<administrative transfer to H10W 72/01251 and H10W 72/072 simultaneously>

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D	H01L2224/81945	6	using a corona discharge, e.g. electronic flame off [EFO]	<administrative transfer to H10W 72/01251 and H10W 72/072 simultaneously>
D	H01L2224/81947	5	by mechanical means, e.g. "pull-and-cut", pressing, stamping	<administrative transfer to H10W 72/01251 and H10W 72/072 simultaneously>
D	H01L2224/81948	4	Thermal treatments, e.g. annealing, controlled cooling	<administrative transfer to H10W 72/012 and H10W 72/072 simultaneously>
D	H01L2224/81951	4	Forming additional members, e.g. for reinforcing	<administrative transfer to H10W 72/01208 and H10W 72/072 simultaneously>
D	H01L2224/81986	3	Specific sequence of steps, e.g. repetition of manufacturing steps, time sequence	<administrative transfer to H10W 72/072>
D	H01L2224/82	2	by forming build-up interconnects at chip-level, e.g. for high density interconnects [HDI]	<administrative transfer to H10W 70/093>
D	H01L2224/82001	3	involving a temporary auxiliary member not forming part of the bonding apparatus	<administrative transfer to H10W 70/093>
D	H01L2224/82002	4	being a removable or sacrificial coating	<administrative transfer to H10W 70/093>
D	H01L2224/82005	4	being a temporary or sacrificial substrate	<administrative transfer to H10W 70/093>
D	H01L2224/82007	3	involving a permanent auxiliary member being left in the finished device, e.g. aids for holding or protecting a build-up interconnect during or after the bonding process	<administrative transfer to H10W 70/093>
D	H01L2224/82009	3	Pre-treatment of the connector or the bonding area	<administrative transfer to H10W 70/093>
D	H01L2224/8201	4	Cleaning, e.g. oxide removal step, desmearing	<administrative transfer to H10W 70/093>
D	H01L2224/8203	4	Reshaping, e.g. forming vias	<administrative transfer to H10W 70/093>
D	H01L2224/82031	5	by chemical means, e.g. etching, anodisation	<administrative transfer to H10W 70/093>
D	H01L2224/82035	5	by heating means	<administrative transfer to H10W 70/093>
D	H01L2224/82039	6	using a laser	<administrative transfer to H10W 70/093>
D	H01L2224/82045	6	using a corona discharge, e.g. electronic flame off [EFO]	<administrative transfer to H10W 70/093>
D	H01L2224/82047	5	by mechanical means, e.g. severing, pressing, stamping	<administrative transfer to H10W 70/093>
D	H01L2224/82048	4	Thermal treatments, e.g. annealing, controlled pre-heating or pre-cooling	<administrative transfer to H10W 70/093>

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D	H01L2224/82051	4	Forming additional members	<administrative transfer to H10W 70/093>
D	H01L2224/82053	3	Bonding environment	<administrative transfer to H10W 70/093>
D	H01L2224/82054	4	Composition of the atmosphere	<administrative transfer to H10W 70/093>
D	H01L2224/82085	4	being a liquid, e.g. for fluidic self-assembly	<administrative transfer to H10W 70/093>
D	H01L2224/8209	4	Vacuum	<administrative transfer to H10W 70/093>
D	H01L2224/82091	4	Under pressure	<administrative transfer to H10W 70/093>
D	H01L2224/82095	4	Temperature settings	<administrative transfer to H10W 70/093>
D	H01L2224/82096	5	Transient conditions	<administrative transfer to H10W 70/093>
D	H01L2224/82097	6	Heating	<administrative transfer to H10W 70/093>
D	H01L2224/82098	6	Cooling	<administrative transfer to H10W 70/093>
D	H01L2224/82099	5	Ambient temperature	<administrative transfer to H10W 70/093>
D	H01L2224/821	3	Forming a build-up interconnect	<administrative transfer to H10W 70/093>
D	H01L2224/82101	4	by additive methods, e.g. direct writing	<administrative transfer to H10W 70/093>
D	H01L2224/82102	5	using jetting, e.g. ink jet	<administrative transfer to H10W 70/093>
D	H01L2224/82103	5	using laser direct writing	<administrative transfer to H10W 70/093>
D	H01L2224/82104	5	using screen printing	<administrative transfer to H10W 70/093>
D	H01L2224/82105	5	by using a preform	<administrative transfer to H10W 70/093>
D	H01L2224/82106	4	by subtractive methods	<administrative transfer to H10W 70/093>
D	H01L2224/82108	4	by self-assembly processes	<administrative transfer to H10W 70/093>
D	H01L2224/8211	3	involving protection against electrical discharge, e.g. removing electrostatic charge	<administrative transfer to H10W 70/093>
D	H01L2224/8212	3	Aligning	<administrative transfer to H10W 70/093>
D	H01L2224/82121	4	Active alignment, i.e. by apparatus steering, e.g. optical alignment using marks or sensors	<administrative transfer to H10W 70/093>
D	H01L2224/82122	5	by detecting inherent features of, or outside, the semiconductor or solid-state body	<administrative transfer to H10W 70/093>
D	H01L2224/8213	5	using marks formed on the semiconductor or solid-state body	<administrative transfer to H10W 70/093>

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D	H01L2224/82132	5	using marks formed outside the semiconductor or solid-state body, i.e. "off-chip"	<administrative transfer to H10W 70/093>
D	H01L2224/82136	4	involving guiding structures, e.g. spacers or supporting members	<administrative transfer to H10W 70/093>
D	H01L2224/82138	5	the guiding structures being at least partially left in the finished device	<administrative transfer to H10W 70/093>
D	H01L2224/82143	4	Passive alignment, i.e. self alignment, e.g. using surface energy, chemical reactions, thermal equilibrium	<administrative transfer to H10W 70/093>
D	H01L2224/82148	4	involving movement of a part of the bonding apparatus	<administrative transfer to H10W 70/093>
D	H01L2224/82149	5	being the lower part of the bonding apparatus, i.e. holding means for the bodies to be connected, e.g. XY table	<administrative transfer to H10W 70/093>
D	H01L2224/8215	6	Rotational movements	<administrative transfer to H10W 70/093>
D	H01L2224/8216	6	Translational movements	<administrative transfer to H10W 70/093>
D	H01L2224/82169	5	being the upper part of the bonding apparatus, e.g. nozzle	<administrative transfer to H10W 70/093>
D	H01L2224/8217	6	Rotational movement	<administrative transfer to H10W 70/093>
D	H01L2224/8218	6	Translational movements	<administrative transfer to H10W 70/093>
D	H01L2224/82181	7	connecting first on the semiconductor or solid-state body, i.e. on-chip,	<administrative transfer to H10W 70/093>
D	H01L2224/82186	7	connecting first outside the semiconductor or solid-state body, i.e. off-chip	<administrative transfer to H10W 70/093>
D	H01L2224/82191	7	connecting first both on and outside the semiconductor or solid-state body	<administrative transfer to H10W 70/093>
D	H01L2224/822	3	Applying energy for connecting	<administrative transfer to H10W 70/093>
D	H01L2224/82201	4	Compression bonding	<administrative transfer to H10W 70/093>
D	H01L2224/82203	5	Thermocompression bonding	<administrative transfer to H10W 70/093>
D	H01L2224/82205	5	Ultrasonic bonding	<administrative transfer to H10W 70/093>
D	H01L2224/82207	6	Thermosonic bonding	<administrative transfer to H10W 70/093>
D	H01L2224/8221	4	with energy being in the form of electromagnetic radiation	<administrative transfer to H10W 70/093>
D	H01L2224/82212	5	Induction heating, i.e. eddy currents	<administrative transfer to H10W 70/093>
D	H01L2224/82214	5	using a laser	<administrative transfer to H10W 70/093>

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D	H01L2224/8223	5	Polychromatic or infrared lamp heating	<administrative transfer to H10W 70/093>
D	H01L2224/82232	4	using an autocatalytic reaction, e.g. exothermic brazing	<administrative transfer to H10W 70/093>
D	H01L2224/82234	4	using means for applying energy being within the device, e.g. integrated heater	<administrative transfer to H10W 70/093>
D	H01L2224/82236	4	using electro-static corona discharge	<administrative transfer to H10W 70/093>
D	H01L2224/82237	4	using electron beam	<administrative transfer to H10W 70/093>
D	H01L2224/82238	4	using electric resistance welding, i.e. ohmic heating	<administrative transfer to H10W 70/093>
D	H01L2224/8234	3	Bonding interfaces of the connector	<administrative transfer to H10W 70/093>
D	H01L2224/82345	4	Shape, e.g. interlocking features	<administrative transfer to H10W 70/093>
D	H01L2224/82355	4	having an external coating, e.g. protective bond-through coating	<administrative transfer to H10W 70/093>
D	H01L2224/82359	4	Material	<administrative transfer to H10W 70/093>
D	H01L2224/8236	3	Bonding interfaces of the semiconductor or solid state body	<administrative transfer to H10W 70/093>
D	H01L2224/82365	4	Shape, e.g. interlocking features	<administrative transfer to H10W 70/093>
D	H01L2224/82375	4	having an external coating, e.g. protective bond-through coating	<administrative transfer to H10W 70/093>
D	H01L2224/82379	4	Material	<administrative transfer to H10W 70/093>
D	H01L2224/8238	3	Bonding interfaces outside the semiconductor or solid-state body	<administrative transfer to H10W 70/093>
D	H01L2224/82385	4	Shape, e.g. interlocking features	<administrative transfer to H10W 70/093>
D	H01L2224/82395	4	having an external coating, e.g. protective bond-through coating	<administrative transfer to H10W 70/093>
D	H01L2224/82399	4	Material	<administrative transfer to H10W 70/093>
D	H01L2224/828	3	Bonding techniques	<administrative transfer to H10W 70/093>
D	H01L2224/82801	4	Soldering or alloying	<administrative transfer to H10W 70/093>
D	H01L2224/82805	5	involving forming a eutectic alloy at the bonding interface	<administrative transfer to H10W 70/093>
D	H01L2224/8281	5	involving forming an intermetallic compound at the bonding interface	<administrative transfer to H10W 70/093>
D	H01L2224/82815	5	Reflow soldering	<administrative transfer to H10W 70/093>
D	H01L2224/8282	5	Diffusion bonding	<administrative transfer to H10W 70/093>

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D	H01L2224/82825	6	Solid-liquid interdiffusion	<administrative transfer to H10W 70/093>
D	H01L2224/8283	6	Solid-solid interdiffusion	<administrative transfer to H10W 70/093>
D	H01L2224/8284	4	Sintering	<administrative transfer to H10W 70/093>
D	H01L2224/8285	4	using a polymer adhesive, e.g. an adhesive based on silicone, epoxy, polyimide, polyester	<administrative transfer to H10W 70/093>
D	H01L2224/82855	5	Hardening the adhesive by curing, i.e. thermosetting	<administrative transfer to H10W 70/093>
D	H01L2224/82856	6	Pre-cured adhesive, i.e. B-stage adhesive	<administrative transfer to H10W 70/093>
D	H01L2224/82859	6	Localised curing of parts of the connector	<administrative transfer to H10W 70/093>
D	H01L2224/82862	6	Heat curing	<administrative transfer to H10W 70/093>
D	H01L2224/82865	6	Microwave curing	<administrative transfer to H10W 70/093>
D	H01L2224/82868	6	Infrared [IR] curing	<administrative transfer to H10W 70/093>
D	H01L2224/82871	6	Visible light curing	<administrative transfer to H10W 70/093>
D	H01L2224/82874	6	Ultraviolet [UV] curing	<administrative transfer to H10W 70/093>
D	H01L2224/82877	6	Moisture curing, i.e. curing by exposing to humidity, e.g. for silicones and polyurethanes	<administrative transfer to H10W 70/093>
D	H01L2224/8288	5	Hardening the adhesive by cooling, e.g. for thermoplastics or hot-melt adhesives	<administrative transfer to H10W 70/093>
D	H01L2224/82885	5	Combinations of two or more hardening methods provided for in at least two different groups from H01L2224/82855 - H01L2224/8288, e.g. for hybrid thermoplastic-thermosetting adhesives	<administrative transfer to H10W 70/093>
D	H01L2224/8289	4	using an inorganic non metallic glass type adhesive, e.g. solder glass	<administrative transfer to H10W 70/093>
D	H01L2224/82893	4	Anodic bonding, i.e. bonding by applying a voltage across the interface in order to induce ions migration leading to an irreversible chemical bond	<administrative transfer to H10W 70/093>
D	H01L2224/82895	4	Direct bonding, i.e. joining surfaces by means of intermolecular attracting interactions at their interfaces, e.g. covalent bonds, van der Waals forces	<administrative transfer to H10W 70/093>
D	H01L2224/82896	5	between electrically conductive surfaces, e.g. copper-copper direct bonding, surface activated bonding	<administrative transfer to H10W 70/093>
D	H01L2224/82897	5	between electrically insulating surfaces, e.g. oxide or nitride layers	<administrative transfer to H10W 70/093>

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D	H01L2224/82899	4	Combinations of bonding methods provided for in at least two different groups from H01L2224/828 - H01L2224/82897	<administrative transfer to H10W 70/093>
D	H01L2224/829	3	involving monitoring, e.g. feedback loop	<administrative transfer to H10W 70/093>
D	H01L2224/82909	3	Post-treatment of the connector or the bonding area	<administrative transfer to H10W 70/093>
D	H01L2224/8291	4	Cleaning, e.g. oxide removal step, desmearing	<administrative transfer to H10W 70/093>
D	H01L2224/8293	4	Reshaping	<administrative transfer to H10W 70/093>
D	H01L2224/82931	5	by chemical means, e.g. etching, anodisation	<administrative transfer to H10W 70/093>
D	H01L2224/82935	5	by heating means	<administrative transfer to H10W 70/093>
D	H01L2224/82939	6	using a laser	<administrative transfer to H10W 70/093>
D	H01L2224/82945	6	using a corona discharge, e.g. electronic flame off [EFO]	<administrative transfer to H10W 70/093>
D	H01L2224/82947	5	by mechanical means, e.g. severing, pressing, stamping	<administrative transfer to H10W 70/093>
D	H01L2224/82948	4	Thermal treatments, e.g. annealing, controlled pre-heating or pre-cooling	<administrative transfer to H10W 70/093>
D	H01L2224/82951	4	Forming additional members	<administrative transfer to H10W 70/093>
D	H01L2224/82986	3	Specific sequence of steps, e.g. repetition of manufacturing steps, time sequence	<administrative transfer to H10W 70/093>
D	H01L2224/83	2	using a layer connector	<administrative transfer to H10W 72/073>
D	H01L2224/83001	3	involving a temporary auxiliary member not forming part of the bonding apparatus	<administrative transfer to H10W 72/07304>
D	H01L2224/83002	4	being a removable or sacrificial coating	<administrative transfer to H10W 72/07304>
D	H01L2224/83005	4	being a temporary or sacrificial substrate	<administrative transfer to H10W 72/07307>
D	H01L2224/83007	3	involving a permanent auxiliary member being left in the finished device, e.g. aids for holding or protecting the layer connector during or after the bonding process	<administrative transfer to H10W 72/07302>
D	H01L2224/83009	3	Pre-treatment of the layer connector or the bonding area	<administrative transfer to H10W 72/07311>
D	H01L2224/8301	4	Cleaning the layer connector, e.g. oxide removal step, desmearing	<administrative transfer to H10W 72/07311 and H10W 72/01371 simultaneously>
D	H01L2224/83011	5	Chemical cleaning, e.g. etching, flux	<administrative transfer to H10W 72/07311 and

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				H10W 72/01371 simultaneously>
D	H01L2224/83012	5	Mechanical cleaning, e.g. abrasion using hydro blasting, brushes, ultrasonic cleaning, dry ice blasting, gas-flow	<administrative transfer to H10W 72/07311 and H10W 72/01371 simultaneously>
D	H01L2224/83013	5	Plasma cleaning	<administrative transfer to H10W 72/07311 and H10W 72/01371 simultaneously>
D	H01L2224/83014	5	Thermal cleaning, e.g. decomposition, sublimation	<administrative transfer to H10W 72/07311 and H10W 72/01371 simultaneously>
D	H01L2224/83019	5	Combinations of two or more cleaning methods provided for in at least two different groups from H01L2224/8301 - H01L2224/83014	<administrative transfer to H10W 72/07311 and H10W 72/01371 simultaneously>
D	H01L2224/8302	4	Applying permanent coating to the layer connector in the bonding apparatus, e.g. in-situ coating	<administrative transfer to H10W 72/07311 and H10W 72/01315 simultaneously>
D	H01L2224/83022	4	Cleaning the bonding area, e.g. oxide removal step, desmearing	<administrative transfer to H10W 72/07311 and H10W 72/01371 simultaneously>
D	H01L2224/83024	4	Applying flux to the bonding area	<administrative transfer to H10W 72/07311 and H10W 72/013 simultaneously>
D	H01L2224/83026	4	Applying a precursor material to the bonding area	<administrative transfer to H10W 72/07311 and H10W 72/013 simultaneously>
D	H01L2224/8303	4	Reshaping the layer connector in the bonding apparatus, e.g. flattening the layer connector	<administrative transfer to H10W 72/07311 and H10W 72/01351 simultaneously>
D	H01L2224/83031	5	by chemical means, e.g. etching, anodisation	<administrative transfer to H10W 72/07311 and H10W 72/01353 simultaneously>
D	H01L2224/83035	5	by heating means	<administrative transfer to H10W 72/07311 and H10W 72/01357 simultaneously>
D	H01L2224/83037	6	using a polychromatic heating lamp	<administrative transfer to H10W 72/07311 and H10W 72/01357 simultaneously>

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D	H01L2224/83039	6	using a laser	<administrative transfer to H10W 72/07311 and H10W 72/01357 simultaneously>
D	H01L2224/83041	6	Induction heating, i.e. eddy currents	<administrative transfer to H10W 72/07311 and H10W 72/01357 simultaneously>
D	H01L2224/83047	5	by mechanical means, e.g. severing, pressing, stamping	<administrative transfer to H10W 72/07311 and H10W 72/01351 simultaneously>
D	H01L2224/83048	4	Thermal treatments, e.g. annealing, controlled pre-heating or pre-cooling	<administrative transfer to H10W 72/07311 and H10W 72/01365 simultaneously>
D	H01L2224/83051	4	Forming additional members, e.g. dam structures	<administrative transfer to H10W 72/07311>
D	H01L2224/83052	3	Detaching layer connectors, e.g. after testing	<administrative transfer to H10W 72/073>
D	H01L2224/83053	3	Bonding environment	<administrative transfer to H10W 72/07341>
D	H01L2224/83054	4	Composition of the atmosphere	<administrative transfer to H10W 72/07341>
D	H01L2224/83055	5	being oxidating	<administrative transfer to H10W 72/07341>
D	H01L2224/83065	5	being reducing	<administrative transfer to H10W 72/07341>
D	H01L2224/83075	5	being inert	<administrative transfer to H10W 72/07341>
D	H01L2224/83085	4	being a liquid, e.g. for fluidic self-assembly	<administrative transfer to H10W 72/07341>
D	H01L2224/8309	4	Vacuum	<administrative transfer to H10W 72/07341>
D	H01L2224/83091	4	Under pressure	<administrative transfer to H10W 72/07341>
D	H01L2224/83092	5	Atmospheric pressure	<administrative transfer to H10W 72/07341>
D	H01L2224/83093	5	Transient conditions, e.g. gas-flow	<administrative transfer to H10W 72/07341>
D	H01L2224/83095	4	Temperature settings	<administrative transfer to H10W 72/07341>
D	H01L2224/83096	5	Transient conditions	<administrative transfer to H10W 72/07341>
D	H01L2224/83097	6	Heating	<administrative transfer to H10W 72/07341>
D	H01L2224/83098	6	Cooling	<administrative transfer to H10W 72/07341>

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D	H01L2224/83099	5	Ambient temperature	<administrative transfer to H10W 72/07341>
D	H01L2224/831	3	the layer connector being supplied to the parts to be connected in the bonding apparatus	<administrative transfer to H10W 72/073>
D	H01L2224/83101	4	as prepreg comprising a layer connector, e.g. provided in an insulating plate member	<administrative transfer to H10W 72/073>
D	H01L2224/83102	4	using surface energy, e.g. capillary forces	<administrative transfer to H10W 72/073>
D	H01L2224/83104	4	by applying pressure, e.g. by injection	<administrative transfer to H10W 72/073>
D	H01L2224/8311	3	involving protection against electrical discharge, e.g. removing electrostatic charge	<administrative transfer to H10W 72/073>
D	H01L2224/8312	3	Aligning	<administrative transfer to H10W 72/07321>
D	H01L2224/83121	4	Active alignment, i.e. by apparatus steering, e.g. optical alignment using marks or sensors	<administrative transfer to H10W 72/07323>
D	H01L2224/83122	5	by detecting inherent features of, or outside, the semiconductor or solid-state body	<administrative transfer to H10W 72/07323>
D	H01L2224/83123	6	Shape or position of the body	<administrative transfer to H10W 72/07323>
D	H01L2224/83125	6	Bonding areas on the body	<administrative transfer to H10W 72/07323>
D	H01L2224/83127	6	Bonding areas outside the body	<administrative transfer to H10W 72/07323>
D	H01L2224/83129	6	Shape or position of the other item	<administrative transfer to H10W 72/07323>
D	H01L2224/8313	5	using marks formed on the semiconductor or solid-state body	<administrative transfer to H10W 72/07323>
D	H01L2224/83132	5	using marks formed outside the semiconductor or solid-state body, i.e. "off-chip"	<administrative transfer to H10W 72/07323>
D	H01L2224/83136	4	involving guiding structures, e.g. spacers or supporting members	<administrative transfer to H10W 72/07327>
D	H01L2224/83138	5	the guiding structures being at least partially left in the finished device	<administrative transfer to H10W 72/07327>
D	H01L2224/83139	6	Guiding structures on the body	<administrative transfer to H10W 72/07327>
D	H01L2224/8314	6	Guiding structures outside the body	<administrative transfer to H10W 72/07327>
D	H01L2224/83141	6	Guiding structures both on and outside the body	<administrative transfer to H10W 72/07327>
D	H01L2224/83143	4	Passive alignment, i.e. self alignment, e.g. using surface energy, chemical reactions, thermal equilibrium	<administrative transfer to H10W 72/07321>
D	H01L2224/83148	4	involving movement of a part of the bonding apparatus	<administrative transfer to H10W 72/073>

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D	H01L2224/83149	5	being the lower part of the bonding apparatus, i.e. holding means for the bodies to be connected, e.g. XY table	<administrative transfer to H10W 72/073>
D	H01L2224/8315	6	Rotational movements	<administrative transfer to H10W 72/073>
D	H01L2224/8316	6	Translational movements	<administrative transfer to H10W 72/073>
D	H01L2224/83169	5	being the upper part of the bonding apparatus, i.e. bonding head	<administrative transfer to H10W 72/073>
D	H01L2224/8317	6	Rotational movements	<administrative transfer to H10W 72/073>
D	H01L2224/8318	6	Translational movements	<administrative transfer to H10W 72/073>
D	H01L2224/8319	3	Arrangement of the layer connectors prior to mounting	<administrative transfer to H10W 72/073>
D	H01L2224/83191	4	wherein the layer connectors are disposed only on the semiconductor or solid-state body	<administrative transfer to H10W 72/073>
D	H01L2224/83192	4	wherein the layer connectors are disposed only on another item or body to be connected to the semiconductor or solid-state body	<administrative transfer to H10W 72/073>
D	H01L2224/83193	4	wherein the layer connectors are disposed on both the semiconductor or solid-state body and another item or body to be connected to the semiconductor or solid-state body	<administrative transfer to H10W 72/073>
D	H01L2224/83194	4	Lateral distribution of the layer connectors	<administrative transfer to H10W 72/073>
D	H01L2224/832	3	Applying energy for connecting	<administrative transfer to H10W 72/07331>
D	H01L2224/83201	4	Compression bonding	<administrative transfer to H10W 72/07332>
D	H01L2224/83203	5	Thermocompression bonding, e.g. diffusion bonding, pressure joining, thermocompression welding or solid-state welding	<administrative transfer to H10W 72/07332>
D	H01L2224/83204	6	with a graded temperature profile	<administrative transfer to H10W 72/07332>
D	H01L2224/83205	5	Ultrasonic bonding	<administrative transfer to H10W 72/07333>
D	H01L2224/83206	6	Direction of oscillation	<administrative transfer to H10W 72/07333>
D	H01L2224/83207	6	Thermosonic bonding	<administrative transfer to H10W 72/07333>
D	H01L2224/83208	5	applying unidirectional static pressure	<administrative transfer to H10W 72/07331>
D	H01L2224/83209	5	applying isostatic pressure, e.g. degassing using vacuum or a pressurised liquid	<administrative transfer to H10W 72/07331>
D	H01L2224/8321	4	using a reflow oven	<administrative transfer to H10W 72/07334>

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D	H01L2224/83211	5	with a graded temperature profile	<administrative transfer to H10W 72/07334>
D	H01L2224/8322	4	with energy being in the form of electromagnetic radiation	<administrative transfer to H10W 72/07335>
D	H01L2224/83222	5	Induction heating, i.e. eddy currents	<administrative transfer to H10W 72/07335>
D	H01L2224/83224	5	using a laser	<administrative transfer to H10W 72/07335>
D	H01L2224/8323	5	Polychromatic or infrared lamp heating	<administrative transfer to H10W 72/07335>
D	H01L2224/83232	4	using an autocatalytic reaction, e.g. exothermic brazing	<administrative transfer to H10W 72/07331>
D	H01L2224/83234	4	using means for applying energy being within the device, e.g. integrated heater	<administrative transfer to H10W 72/07331>
D	H01L2224/83236	4	using electro-static corona discharge	<administrative transfer to H10W 72/07331>
D	H01L2224/83237	4	using an electron beam	<administrative transfer to H10W 72/07331>
D	H01L2224/83238	4	using electric resistance welding, i.e. ohmic heating	<administrative transfer to H10W 72/07331>
D	H01L2224/8334	3	Bonding interfaces of the layer connector	<administrative transfer to H10W 72/073>
D	H01L2224/83345	4	Shape, e.g. interlocking features	<administrative transfer to H10W 72/073 and H10W 72/331 simultaneously>
D	H01L2224/83355	4	having an external coating, e.g. protective bond-through coating	<administrative transfer to H10W 72/073 and H10W 72/322 simultaneously>
D	H01L2224/83359	4	Material	<administrative transfer to H10W 72/073 and H10W 72/351 simultaneously>
D	H01L2224/8336	3	Bonding interfaces of the semiconductor or solid state body	<administrative transfer to H10W 72/90>
D	H01L2224/83365	4	Shape, e.g. interlocking features	<administrative transfer to H10W 72/931>
D	H01L2224/83375	4	having an external coating, e.g. protective bond-through coating	<administrative transfer to H10W 72/923>
D	H01L2224/83379	4	Material	<administrative transfer to H10W 72/951>
D	H01L2224/8338	3	Bonding interfaces outside the semiconductor or solid-state body	<administrative transfer to H10W 72/90>
D	H01L2224/83385	4	Shape, e.g. interlocking features	<administrative transfer to H10W 72/931>
D	H01L2224/83395	4	having an external coating, e.g. protective bond-through coating	<administrative transfer to H10W 72/923>

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D	H01L2224/83399	4	Material	<administrative transfer to H10W 72/951>
D	H01L2224/834	5	with a principal constituent of the material being a metal or a metalloid, e.g. boron [B], silicon [Si], germanium [Ge], arsenic [As], antimony [Sb], tellurium [Te] and polonium [Po], and alloys thereof	<administrative transfer to H10W 72/952>
D	H01L2224/83401	6	the principal constituent melting at a temperature of less than 400°C	<administrative transfer to H10W 72/952>
D	H01L2224/83405	7	Gallium [Ga] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/83409	7	Indium [In] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/83411	7	Tin [Sn] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/83413	7	Bismuth [Bi] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/83414	7	Thallium [Tl] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/83416	7	Lead [Pb] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/83417	6	the principal constituent melting at a temperature of greater than or equal to 400°C and less than 950°C	<administrative transfer to H10W 72/952>
D	H01L2224/83418	7	Zinc [Zn] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/8342	7	Antimony [Sb] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/83423	7	Magnesium [Mg] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/83424	7	Aluminium [Al] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/83438	6	the principal constituent melting at a temperature of greater than or equal to 950°C and less than 1550°C	<administrative transfer to H10W 72/952>
D	H01L2224/83439	7	Silver [Ag] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/83444	7	Gold [Au] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/83447	7	Copper [Cu] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/83449	7	Manganese [Mn] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/83455	7	Nickel [Ni] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/83457	7	Cobalt [Co] as principal constituent	<administrative transfer to H10W 72/952>

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D	H01L2224/8346	7	Iron [Fe] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/83463	6	the principal constituent melting at a temperature of greater than 1550°C	<administrative transfer to H10W 72/952>
D	H01L2224/83464	7	Palladium [Pd] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/83466	7	Titanium [Ti] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/83469	7	Platinum [Pt] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/8347	7	Zirconium [Zr] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/83471	7	Chromium [Cr] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/83472	7	Vanadium [V] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/83473	7	Rhodium [Rh] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/83476	7	Ruthenium [Ru] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/83478	7	Iridium [Ir] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/83479	7	Niobium [Nb] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/8348	7	Molybdenum [Mo] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/83481	7	Tantalum [Ta] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/83483	7	Rhenium [Re] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/83484	7	Tungsten [W] as principal constituent	<administrative transfer to H10W 72/952>
D	H01L2224/83486	5	with a principal constituent of the material being a non metallic, non metalloid inorganic material	<administrative transfer to H10W 72/953>
D	H01L2224/83487	6	Ceramics, e.g. crystalline carbides, nitrides or oxides	<administrative transfer to H10W 72/953>
D	H01L2224/83488	6	Glasses, e.g. amorphous oxides, nitrides or fluorides	<administrative transfer to H10W 72/953>
D	H01L2224/8349	5	with a principal constituent of the material being a polymer, e.g. polyester, phenolic based polymer, epoxy	<administrative transfer to H10W 72/953>
D	H01L2224/83491	6	The principal constituent being an elastomer, e.g. silicones, isoprene, neoprene	<administrative transfer to H10W 72/953>
D	H01L2224/83493	5	with a principal constituent of the material being a solid not provided for in groups H01L2224/834 - H01L2224/83491, e.g.	<administrative transfer to H10W 72/953>

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			allotropes of carbon, fullerene, graphite, carbon-nanotubes, diamond	
D	H01L2224/83494	5	with a principal constituent of the material being a liquid not provided for in groups H01L2224/834 - H01L2224/83491	<administrative transfer to H10W 72/953>
D	H01L2224/83495	5	with a principal constituent of the material being a gas not provided for in groups H01L2224/834 - H01L2224/83491	<administrative transfer to H10W 72/953>
D	H01L2224/83498	5	with a principal constituent of the material being a combination of two or more materials in the form of a matrix with a filler, i.e. being a hybrid material, e.g. segmented structures, foams	<administrative transfer to H10W 72/925 and H10W 72/951 simultaneously>
D	H01L2224/83499	6	Material of the matrix	<administrative transfer to H10W 72/925 and H10W 72/951 simultaneously>
D	H01L2224/835	7	with a principal constituent of the material being a metal or a metalloid, e.g. boron [B], silicon [Si], germanium [Ge], arsenic [As], antimony [Sb], tellurium [Te] and polonium [Po], and alloys thereof	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/83501	8	the principal constituent melting at a temperature of less than 400°C	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/83505	9	Gallium [Ga] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/83509	9	Indium [In] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/83511	9	Tin [Sn] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/83513	9	Bismuth [Bi] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/83514	9	Thallium [Tl] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/83516	9	Lead [Pb] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>

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D	H01L2224/83517	8	the principal constituent melting at a temperature of greater than or equal to 400°C and less than 950°C	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/83518	9	Zinc [Zn] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/8352	9	Antimony [Sb] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/83523	9	Magnesium [Mg] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/83524	9	Aluminium [Al] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/83538	8	the principal constituent melting at a temperature of greater than or equal to 950°C and less than 1550°C	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/83539	9	Silver [Ag] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/83544	9	Gold [Au] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/83547	9	Copper [Cu] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/83549	9	Manganese [Mn] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/83555	9	Nickel [Ni] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/83557	9	Cobalt [Co] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/8356	9	Iron [Fe] as principal constituent	<administrative transfer to H10W 72/925 and

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				H10W 72/952 simultaneously>
D	H01L2224/83563	8	the principal constituent melting at a temperature of greater than 1550°C	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/83564	9	Palladium [Pd] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/83566	9	Titanium [Ti] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/83569	9	Platinum [Pt] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/8357	9	Zirconium [Zr] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/83571	9	Chromium [Cr] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/83572	9	Vanadium [V] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/83573	9	Rhodium [Rh] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/83576	9	Ruthenium [Ru] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/83578	9	Iridium [Ir] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/83579	9	Niobium [Nb] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/8358	9	Molybdenum [Mo] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>

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D	H01L2224/83581	9	Tantalum [Ta] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/83583	9	Rhenium [Re] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/83584	9	Tungsten [W] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/83586	7	with a principal constituent of the material being a non metallic, non metalloid inorganic material	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>
D	H01L2224/83587	8	Ceramics, e.g. crystalline carbides, nitrides or oxides	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>
D	H01L2224/83588	8	Glasses, e.g. amorphous oxides, nitrides or fluorides	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>
D	H01L2224/8359	7	with a principal constituent of the material being a polymer, e.g. polyester, phenolic based polymer, epoxy	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>
D	H01L2224/83591	8	The principal constituent being an elastomer, e.g. silicones, isoprene, neoprene	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>
D	H01L2224/83593	7	with a principal constituent of the material being a solid not provided for in groups H01L2224/835 - H01L2224/83591, e.g. allotropes of carbon, fullerene, graphite, carbon-nanotubes, diamond	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>
D	H01L2224/83594	7	with a principal constituent of the material being a liquid not provided for in groups H01L2224/835 - H01L2224/83591	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>
D	H01L2224/83595	7	with a principal constituent of the material being a gas not provided for in groups H01L2224/835 - H01L2224/83591	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>
D	H01L2224/83598	6	Fillers	<administrative transfer to H10W 72/925 and H10W 72/951 simultaneously>

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D	H01L2224/83599	7	Base material	<administrative transfer to H10W 72/925 and H10W 72/951 simultaneously>
D	H01L2224/836	8	with a principal constituent of the material being a metal or a metalloid, e.g. boron [B], silicon [Si], germanium [Ge], arsenic [As], antimony [Sb], tellurium [Te] and polonium [Po], and alloys thereof	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/83601	9	the principal constituent melting at a temperature of less than 400°C	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/83605	10	Gallium [Ga] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/83609	10	Indium [In] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/83611	10	Tin [Sn] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/83613	10	Bismuth [Bi] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/83614	10	Thallium [Tl] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/83616	10	Lead [Pb] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/83617	9	the principal constituent melting at a temperature of greater than or equal to 400°C and less than 950°C	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/83618	10	Zinc [Zn] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/8362	10	Antimony [Sb] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>

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D	H01L2224/83623	10	Magnesium [Mg] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/83624	10	Aluminium [Al] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/83638	9	the principal constituent melting at a temperature of greater than or equal to 950°C and less than 1550°C	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/83639	10	Silver [Ag] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/83644	10	Gold [Au] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/83647	10	Copper [Cu] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/83649	10	Manganese [Mn] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/83655	10	Nickel [Ni] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/83657	10	Cobalt [Co] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/8366	10	Iron [Fe] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/83663	9	the principal constituent melting at a temperature of greater than 1550°C	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/83664	10	Palladium [Pd] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/83666	10	Titanium [Ti] as principal constituent	<administrative transfer to H10W 72/925 and

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				H10W 72/952 simultaneously>
D	H01L2224/83669	10	Platinum [Pt] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/8367	10	Zirconium [Zr] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/83671	10	Chromium [Cr] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/83672	10	Vanadium [V] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/83673	10	Rhodium [Rh] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/83676	10	Ruthenium [Ru] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/83678	10	Iridium [Ir] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/83679	10	Niobium [Nb] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/8368	10	Molybdenum [Mo] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/83681	10	Tantalum [Ta] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/83683	10	Rhenium [Re] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/83684	10	Tungsten [W] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>

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D	H01L2224/83686	8	with a principal constituent of the material being a non metallic, non metalloid inorganic material	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>
D	H01L2224/83687	9	Ceramics, e.g. crystalline carbides, nitrides or oxides	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>
D	H01L2224/83688	9	Glasses, e.g. amorphous oxides, nitrides or fluorides	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>
D	H01L2224/8369	8	with a principal constituent of the material being a polymer, e.g. polyester, phenolic based polymer, epoxy	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>
D	H01L2224/83691	9	The principal constituent being an elastomer, e.g. silicones, isoprene, neoprene	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>
D	H01L2224/83693	8	with a principal constituent of the material being a solid not provided for in groups H01L2224/836 - H01L2224/83691, e.g. allotropes of carbon, fullerene, graphite, carbon-nanotubes, diamond	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>
D	H01L2224/83694	8	with a principal constituent of the material being a liquid not provided for in groups H01L2224/836 - H01L2224/83691	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>
D	H01L2224/83695	8	with a principal constituent of the material being a gas not provided for in groups H01L2224/836 - H01L2224/83691	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>
D	H01L2224/83698	8	with a principal constituent of the material being a combination of two or more materials in the form of a matrix with a filler, i.e. being a hybrid material, e.g. segmented structures, foams	<administrative transfer to H10W 72/925 and H10W 72/951 simultaneously>
D	H01L2224/83699	7	Coating material	<administrative transfer to H10W 72/925 and H10W 72/951 simultaneously>
D	H01L2224/837	8	with a principal constituent of the material being a metal or a metalloid, e.g. boron [B], silicon [Si], germanium [Ge], arsenic [As], antimony [Sb], tellurium [Te] and polonium [Po], and alloys thereof	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/83701	9	the principal constituent melting at a temperature of less than 400°C	<administrative transfer to H10W 72/925 and

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				H10W 72/952 simultaneously>
D	H01L2224/83705	10	Gallium [Ga] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/83709	10	Indium [In] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/83711	10	Tin [Sn] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/83713	10	Bismuth [Bi] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/83714	10	Thallium [Tl] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/83716	10	Lead [Pb] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/83717	9	the principal constituent melting at a temperature of greater than or equal to 400°C and less than 950°C	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/83718	10	Zinc [Zn] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/8372	10	Antimony [Sb] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/83723	10	Magnesium [Mg] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/83724	10	Aluminium [Al] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/83738	9	the principal constituent melting at a temperature of greater than or equal to 950°C and less than 1550°C	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>

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D	H01L2224/83739	10	Silver [Ag] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/83744	10	Gold [Au] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/83747	10	Copper [Cu] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/83749	10	Manganese [Mn] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/83755	10	Nickel [Ni] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/83757	10	Cobalt [Co] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/8376	10	Iron [Fe] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/83763	9	the principal constituent melting at a temperature of greater than 1550°C	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/83764	10	Palladium [Pd] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/83766	10	Titanium [Ti] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/83769	10	Platinum [Pt] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/8377	10	Zirconium [Zr] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/83771	10	Chromium [Cr] as principal constituent	<administrative transfer to H10W 72/925 and

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				H10W 72/952 simultaneously>
D	H01L2224/83772	10	Vanadium [V] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/83773	10	Rhodium [Rh] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/83776	10	Ruthenium [Ru] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/83778	10	Iridium [Ir] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/83779	10	Niobium [Nb] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/8378	10	Molybdenum [Mo] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/83781	10	Tantalum [Ta] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/83783	10	Rhenium [Re] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/83784	10	Tungsten [W] as principal constituent	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/83786	8	with a principal constituent of the material being a non metallic, non metalloid inorganic material	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>
D	H01L2224/83787	9	Ceramics, e.g. crystalline carbides, nitrides or oxides	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>
D	H01L2224/83788	9	Glasses, e.g. amorphous oxides, nitrides or fluorides	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>

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D	H01L2224/8379	8	with a principal constituent of the material being a polymer, e.g. polyester, phenolic based polymer, epoxy	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>
D	H01L2224/83791	9	The principal constituent being an elastomer, e.g. silicones, isoprene, neoprene	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>
D	H01L2224/83793	8	with a principal constituent of the material being a solid not provided for in groups H01L2224/837 - H01L2224/83791, e.g. allotropes of carbon, fullerene, graphite, carbon-nanotubes, diamond	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>
D	H01L2224/83794	8	with a principal constituent of the material being a liquid not provided for in groups H01L2224/837 - H01L2224/83791	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>
D	H01L2224/83795	8	with a principal constituent of the material being a gas not provided for in groups H01L2224/837 - H01L2224/83791	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>
D	H01L2224/83798	8	with a principal constituent of the material being a combination of two or more materials in the form of a matrix with a filler, i.e. being a hybrid material, e.g. segmented structures, foams	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>
D	H01L2224/83799	7	Shape or distribution of the fillers	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>
D	H01L2224/838	3	Bonding techniques	<administrative transfer to H10W 72/07331>
D	H01L2224/83801	4	Soldering or alloying	<administrative transfer to H10W 72/07336>
D	H01L2224/83805	5	involving forming a eutectic alloy at the bonding interface	<administrative transfer to H10W 72/07336>
D	H01L2224/8381	5	involving forming an intermetallic compound at the bonding interface	<administrative transfer to H10W 72/07336>
D	H01L2224/83815	5	Reflow soldering	<administrative transfer to H10W 72/07336>
D	H01L2224/8382	5	Diffusion bonding	<administrative transfer to H10W 72/07336>
D	H01L2224/83825	6	Solid-liquid interdiffusion	<administrative transfer to H10W 72/07336>
D	H01L2224/8383	6	Solid-solid interdiffusion	<administrative transfer to H10W 72/07336>
D	H01L2224/8384	4	Sintering	<administrative transfer to H10W 72/07331>

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D	H01L2224/8385	4	using a polymer adhesive, e.g. an adhesive based on silicone, epoxy, polyimide, polyester	<administrative transfer to H10W 72/07337>
D	H01L2224/83851	5	being an anisotropic conductive adhesive	<administrative transfer to H10W 72/074>
D	H01L2224/83855	5	Hardening the adhesive by curing, i.e. thermosetting	<administrative transfer to H10W 72/07338>
D	H01L2224/83856	6	Pre-cured adhesive, i.e. B-stage adhesive	<administrative transfer to H10W 72/07338>
D	H01L2224/83859	6	Localised curing of parts of the layer connector	<administrative transfer to H10W 72/07338>
D	H01L2224/83862	6	Heat curing	<administrative transfer to H10W 72/07338>
D	H01L2224/83865	6	Microwave curing	<administrative transfer to H10W 72/07338>
D	H01L2224/83868	6	Infrared [IR] curing	<administrative transfer to H10W 72/07338>
D	H01L2224/83871	6	Visible light curing	<administrative transfer to H10W 72/07338>
D	H01L2224/83874	6	Ultraviolet [UV] curing	<administrative transfer to H10W 72/07338>
D	H01L2224/83877	6	Moisture curing, i.e. curing by exposing to humidity, e.g. for silicones and polyurethanes	<administrative transfer to H10W 72/07338>
D	H01L2224/8388	5	Hardening the adhesive by cooling, e.g. for thermoplastics or hot-melt adhesives	<administrative transfer to H10W 72/07339>
D	H01L2224/83885	5	Combinations of two or more hardening methods provided for in at least two different groups from H01L2224/83855 - H01L2224/8388, e.g. for hybrid thermoplastic-thermosetting adhesives	<administrative transfer to H10W 72/07331>
D	H01L2224/83886	4	Involving a self-assembly process, e.g. self-agglomeration of a material dispersed in a fluid	<administrative transfer to H10W 72/07331>
D	H01L2224/83887	5	Auxiliary means therefor, e.g. for self-assembly activation	<administrative transfer to H10W 72/07331>
D	H01L2224/83888	5	with special adaptation of the surface of the body to be connected, e.g. surface shape specially adapted for the self-assembly process	<administrative transfer to H10W 72/07331>
D	H01L2224/83889	5	involving the material of the bonding area, e.g. bonding pad	<administrative transfer to H10W 72/07331>
D	H01L2224/8389	4	using an inorganic non metallic glass type adhesive, e.g. solder glass	<administrative transfer to H10W 72/07331>
D	H01L2224/83893	4	Anodic bonding, i.e. bonding by applying a voltage across the interface in order to induce ions migration leading to an irreversible chemical bond	<administrative transfer to H10W 72/07331>
D	H01L2224/83894	4	Direct bonding, i.e. joining surfaces by means of intermolecular attracting interactions at	<administrative transfer to H10W 72/07331>

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			their interfaces, e.g. covalent bonds, van der Waals forces	
D	H01L2224/83895	5	between electrically conductive surfaces, e.g. copper-copper direct bonding, surface activated bonding	<administrative transfer to H10W 72/07331>
D	H01L2224/83896	5	between electrically insulating surfaces, e.g. oxide or nitride layers	<administrative transfer to H10W 72/07331>
D	H01L2224/83897	4	Mechanical interlocking, e.g. anchoring, hook and loop-type fastening or the like	<administrative transfer to H10W 72/07331>
D	H01L2224/83898	5	Press-fitting, i.e. pushing the parts together and fastening by friction, e.g. by compression of one part against the other	<administrative transfer to H10W 72/07331>
D	H01L2224/83899	6	using resilient parts in the layer connector or in the bonding area	<administrative transfer to H10W 72/07331>
D	H01L2224/839	3	with the layer connector not providing any mechanical bonding	<administrative transfer to H10W 72/07331>
D	H01L2224/83901	4	Pressing the layer connector against the bonding areas by means of another connector	<administrative transfer to H10W 72/07331>
D	H01L2224/83902	5	by means of another layer connector	<administrative transfer to H10W 72/07331>
D	H01L2224/83903	5	by means of a bump connector	<administrative transfer to H10W 72/07331>
D	H01L2224/83904	5	by means of an encapsulation layer or foil	<administrative transfer to H10W 72/07331>
D	H01L2224/83905	3	Combinations of bonding methods provided for in at least two different groups from H01L2224/838 - H01L2224/83904	<administrative transfer to H10W 72/07331>
D	H01L2224/83906	4	Specific sequence of method steps	<administrative transfer to H10W 72/07331>
D	H01L2224/83907	4	Intermediate bonding, i.e. intermediate bonding step for temporarily bonding the semiconductor or solid-state body, followed by at least a further bonding step	<administrative transfer to H10W 72/07331>
D	H01L2224/83908	3	involving monitoring, e.g. feedback loop	<administrative transfer to H10W 72/07331>
D	H01L2224/83909	3	Post-treatment of the layer connector or bonding area	<administrative transfer to H10W 72/07331 and H10W 72/013 simultaneously>
D	H01L2224/8391	4	Cleaning, e.g. oxide removal step, desmearing	<administrative transfer to H10W 72/07331 and H10W 72/01371 simultaneously>
D	H01L2224/83911	5	Chemical cleaning, e.g. etching, flux	<administrative transfer to H10W 72/07331 and H10W 72/01371 simultaneously>

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D	H01L2224/83912	5	Mechanical cleaning, e.g. abrasion using hydro blasting, brushes, ultrasonic cleaning, dry ice blasting, gas-flow	<administrative transfer to H10W 72/07331 and H10W 72/01371 simultaneously>
D	H01L2224/83913	5	Plasma cleaning	<administrative transfer to H10W 72/07331 and H10W 72/01371 simultaneously>
D	H01L2224/83914	5	Thermal cleaning, e.g. using laser ablation or by electrostatic corona discharge	<administrative transfer to H10W 72/07331 and H10W 72/01371 simultaneously>
D	H01L2224/83919	5	Combinations of two or more cleaning methods provided for in at least two different groups from H01L2224/8391 - H01L2224/83914	<administrative transfer to H10W 72/07331 and H10W 72/01371 simultaneously>
D	H01L2224/8392	4	Applying permanent coating, e.g. protective coating	<administrative transfer to H10W 72/07331 and H10W 72/01315 simultaneously>
D	H01L2224/8393	4	Reshaping	<administrative transfer to H10W 72/07331 and H10W 72/01351 simultaneously>
D	H01L2224/83931	5	by chemical means, e.g. etching	<administrative transfer to H10W 72/07331 and H10W 72/01353 simultaneously>
D	H01L2224/83935	5	by heating means, e.g. reflowing	<administrative transfer to H10W 72/07331 and H10W 72/01357 simultaneously>
D	H01L2224/83937	6	using a polychromatic heating lamp	<administrative transfer to H10W 72/07331 and H10W 72/01357 simultaneously>
D	H01L2224/83939	6	using a laser	<administrative transfer to H10W 72/07331 and H10W 72/01357 simultaneously>
D	H01L2224/83941	6	Induction heating, i.e. eddy currents	<administrative transfer to H10W 72/07331 and H10W 72/01357 simultaneously>
D	H01L2224/83943	6	using a flame torch, e.g. hydrogen torch	<administrative transfer to H10W 72/07331 and H10W 72/01357 simultaneously>
D	H01L2224/83945	6	using a corona discharge, e.g. electronic flame off [EFO]	<administrative transfer to H10W 72/07331 and

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				H10W 72/01357 simultaneously>
D	H01L2224/83947	5	by mechanical means, e.g. "pull-and-cut", pressing, stamping	<administrative transfer to H10W 72/07331 and H10W 72/01351 simultaneously>
D	H01L2224/83948	4	Thermal treatments, e.g. annealing, controlled cooling	<administrative transfer to H10W 72/07331 and H10W 72/01365 simultaneously>
D	H01L2224/83951	4	Forming additional members, e.g. for reinforcing, fillet sealant	<administrative transfer to H10W 72/07331>
D	H01L2224/83986	3	Specific sequence of steps, e.g. repetition of manufacturing steps, time sequence	<administrative transfer to H10W 72/07331>
D	H01L2224/84	2	using a strap connector	<administrative transfer to H10W 72/076>
D	H01L2224/84001	3	involving a temporary auxiliary member not forming part of the bonding apparatus	<administrative transfer to H10W 72/07604>
D	H01L2224/84002	4	being a removable or sacrificial coating	<administrative transfer to H10W 72/07604>
D	H01L2224/84005	4	being a temporary substrate	<administrative transfer to H10W 72/07607>
D	H01L2224/84007	3	involving a permanent auxiliary member being left in the finished device, e.g. aids for holding or protecting the strap connector during or after the bonding process	<administrative transfer to H10W 72/07602>
D	H01L2224/84009	3	Pre-treatment of the connector and/or the bonding area	<administrative transfer to H10W 72/07611 and H10W 72/016 simultaneously>
D	H01L2224/8401	4	Cleaning, e.g. oxide removal step, desmearing	<administrative transfer to H10W 72/07611 and H10W 72/01671 simultaneously>
D	H01L2224/84011	5	Chemical cleaning, e.g. etching, flux	<administrative transfer to H10W 72/07611 and H10W 72/01671 simultaneously>
D	H01L2224/84012	5	Mechanical cleaning, e.g. abrasion using hydro blasting, brushes, ultrasonic cleaning, dry ice blasting, gas-flow	<administrative transfer to H10W 72/07611 and H10W 72/01671 simultaneously>
D	H01L2224/84013	5	Plasma cleaning	<administrative transfer to H10W 72/07611 and H10W 72/01671 simultaneously>
D	H01L2224/84014	5	Thermal cleaning, e.g. decomposition, sublimation	<administrative transfer to H10W 72/07611 and H10W 72/01671 simultaneously>

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D	H01L2224/84019	5	Combinations of two or more cleaning methods provided for in at least two different groups from H01L2224/8401 - H01L2224/84014	<administrative transfer to H10W 72/07611 and H10W 72/01671 simultaneously>
D	H01L2224/8402	4	Applying permanent coating, e.g. in-situ coating	<administrative transfer to H10W 72/07611 and H10W 72/01615 simultaneously>
D	H01L2224/8403	4	Reshaping	<administrative transfer to H10W 72/07611 and H10W 72/01651 simultaneously>
D	H01L2224/84031	5	by chemical means, e.g. etching, anodisation	<administrative transfer to H10W 72/07611 and H10W 72/01653 simultaneously>
D	H01L2224/84035	5	by heating means, e.g. "free-air-ball"	<administrative transfer to H10W 72/07611 and H10W 72/01651 simultaneously>
D	H01L2224/84037	6	using a polychromatic heating lamp	<administrative transfer to H10W 72/07611 and H10W 72/01651 simultaneously>
D	H01L2224/84039	6	using a laser	<administrative transfer to H10W 72/07611 and H10W 72/01651 simultaneously>
D	H01L2224/84041	6	Induction heating, i.e. eddy currents	<administrative transfer to H10W 72/07611 and H10W 72/01651 simultaneously>
D	H01L2224/84043	6	using a flame torch, e.g. hydrogen torch	<administrative transfer to H10W 72/07611 and H10W 72/01651 simultaneously>
D	H01L2224/84045	6	using a corona discharge, e.g. electronic flame off [EFO]	<administrative transfer to H10W 72/07611 and H10W 72/01651 simultaneously>
D	H01L2224/84047	5	by mechanical means, e.g. severing, pressing, stamping	<administrative transfer to H10W 72/07611 and H10W 72/01651 simultaneously>
D	H01L2224/84048	4	Thermal treatments, e.g. annealing, controlled pre-heating or pre-cooling	<administrative transfer to H10W 72/07611 and H10W 72/016 simultaneously>
D	H01L2224/84051	4	Forming additional members	<administrative transfer to H10W 72/07611 and

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				H10W 72/016 simultaneously>
D	H01L2224/84053	3	Bonding environment	<administrative transfer to H10W 72/07641>
D	H01L2224/84054	4	Composition of the atmosphere	<administrative transfer to H10W 72/07641>
D	H01L2224/84055	5	being oxidating	<administrative transfer to H10W 72/07641>
D	H01L2224/84065	5	being reducing	<administrative transfer to H10W 72/07641>
D	H01L2224/84075	5	being inert	<administrative transfer to H10W 72/07641>
D	H01L2224/84085	4	being a liquid (e.g. for fluidic self-assembly)	<administrative transfer to H10W 72/07641>
D	H01L2224/8409	4	Vacuum	<administrative transfer to H10W 72/07641>
D	H01L2224/84091	4	Under pressure	<administrative transfer to H10W 72/07641>
D	H01L2224/84092	5	Atmospheric pressure	<administrative transfer to H10W 72/07641>
D	H01L2224/84093	5	Transient conditions, e.g. gas-flow	<administrative transfer to H10W 72/07641>
D	H01L2224/84095	4	Temperature settings	<administrative transfer to H10W 72/07641>
D	H01L2224/84096	5	Transient conditions	<administrative transfer to H10W 72/07641>
D	H01L2224/84097	6	Heating	<administrative transfer to H10W 72/07641>
D	H01L2224/84098	6	Cooling	<administrative transfer to H10W 72/07641>
D	H01L2224/84099	5	Ambient temperature	<administrative transfer to H10W 72/07641>
D	H01L2224/841	3	the connector being supplied to the parts to be connected in the bonding apparatus	<administrative transfer to H10W 72/076>
D	H01L2224/8411	3	involving protection against electrical discharge, e.g. removing electrostatic charge	<administrative transfer to H10W 72/076>
D	H01L2224/8412	3	Aligning	<administrative transfer to H10W 72/07621>
D	H01L2224/84121	4	Active alignment, i.e. by apparatus steering, e.g. optical alignment using marks or sensors	<administrative transfer to H10W 72/07623>
D	H01L2224/84122	5	by detecting inherent features of, or outside, the semiconductor or solid-state body	<administrative transfer to H10W 72/07623>
D	H01L2224/84123	6	Shape or position of the body	<administrative transfer to H10W 72/07623>
D	H01L2224/84125	6	Bonding areas on the body	<administrative transfer to H10W 72/07623>
D	H01L2224/84127	6	Bonding areas outside the body	<administrative transfer to H10W 72/07623>

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D	H01L2224/84129	6	Shape or position of the other item	<administrative transfer to H10W 72/07623>
D	H01L2224/8413	5	using marks formed on the semiconductor or solid-state body	<administrative transfer to H10W 72/07623>
D	H01L2224/84132	5	using marks formed outside the semiconductor or solid-state body, i.e. "off-chip"	<administrative transfer to H10W 72/07623>
D	H01L2224/84136	4	involving guiding structures, e.g. spacers or supporting members	<administrative transfer to H10W 72/07627>
D	H01L2224/84138	5	the guiding structures being at least partially left in the finished device	<administrative transfer to H10W 72/07627>
D	H01L2224/84143	4	Passive alignment, i.e. self alignment, e.g. using surface energy, chemical reactions, thermal equilibrium	<administrative transfer to H10W 72/07621>
D	H01L2224/84148	4	involving movement of a part of the bonding apparatus	<administrative transfer to H10W 72/076>
D	H01L2224/84149	5	being the lower part of the bonding apparatus, i.e. holding means for the bodies to be connected, e.g. XY table	<administrative transfer to H10W 72/076>
D	H01L2224/8415	6	Rotational movements	<administrative transfer to H10W 72/076>
D	H01L2224/8416	6	Translational movements	<administrative transfer to H10W 72/076>
D	H01L2224/84169	5	being the upper part of the bonding apparatus, i.e. bonding head,	<administrative transfer to H10W 72/076>
D	H01L2224/8417	6	Rotational movements	<administrative transfer to H10W 72/076>
D	H01L2224/8418	6	Translational movements	<administrative transfer to H10W 72/076>
D	H01L2224/84181	7	connecting first on the semiconductor or solid-state body, i.e. on-chip, regular stitch	<administrative transfer to H10W 72/076>
D	H01L2224/84186	7	connecting first outside the semiconductor or solid-state body, i.e. off-chip, reverse stitch	<administrative transfer to H10W 72/076>
D	H01L2224/84191	7	connecting first both on and outside the semiconductor or solid-state body, i.e. regular and reverse stitches	<administrative transfer to H10W 72/076>
D	H01L2224/84196	7	involving intermediate connecting steps before cutting the strap connector	<administrative transfer to H10W 72/076>
D	H01L2224/842	3	Applying energy for connecting	<administrative transfer to H10W 72/07631>
D	H01L2224/84201	4	Compression bonding	<administrative transfer to H10W 72/07632>
D	H01L2224/84203	5	Thermocompression bonding	<administrative transfer to H10W 72/07632>
D	H01L2224/84205	5	Ultrasonic bonding	<administrative transfer to H10W 72/07633>
D	H01L2224/84206	6	Direction of oscillation	<administrative transfer to H10W 72/07633>

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D	H01L2224/84207	6	Thermosonic bonding	<administrative transfer to H10W 72/07633>
D	H01L2224/8421	4	with energy being in the form of electromagnetic radiation	<administrative transfer to H10W 72/07635>
D	H01L2224/84212	5	Induction heating, i.e. eddy currents	<administrative transfer to H10W 72/07635>
D	H01L2224/84214	5	using a laser	<administrative transfer to H10W 72/07635>
D	H01L2224/8423	5	Polychromatic or infrared lamp heating	<administrative transfer to H10W 72/07635>
D	H01L2224/84232	4	using an autocatalytic reaction, e.g. exothermic brazing	<administrative transfer to H10W 72/07631>
D	H01L2224/84234	4	using means for applying energy being within the device, e.g. integrated heater	<administrative transfer to H10W 72/07631>
D	H01L2224/84236	4	using electro-static corona discharge	<administrative transfer to H10W 72/07631>
D	H01L2224/84237	4	using an electron beam	<administrative transfer to H10W 72/07631>
D	H01L2224/84238	4	using electric resistance welding, i.e. ohmic heating	<administrative transfer to H10W 72/07631>
D	H01L2224/8434	3	Bonding interfaces of the connector	<administrative transfer to H10W 72/076>
D	H01L2224/84345	4	Shape, e.g. interlocking features	<administrative transfer to H10W 72/076 and H10W 72/631 simultaneously>
D	H01L2224/84355	4	having an external coating, e.g. protective bond-through coating	<administrative transfer to H10W 72/076 and H10W 72/621 simultaneously>
D	H01L2224/84359	4	Material	<administrative transfer to H10W 72/076 and H10W 72/651 simultaneously>
D	H01L2224/8436	3	Bonding interfaces of the semiconductor or solid state body	<administrative transfer to H10W 72/076>
D	H01L2224/84365	4	Shape, e.g. interlocking features	<administrative transfer to H10W 72/076 and H10W 72/931 simultaneously>
D	H01L2224/84375	4	having an external coating, e.g. protective bond-through coating	<administrative transfer to H10W 72/076 and H10W 72/923 simultaneously>
D	H01L2224/84379	4	Material	<administrative transfer to H10W 72/076 and H10W 72/951 simultaneously>

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D	H01L2224/8438	3	Bonding interfaces outside the semiconductor or solid-state body	<administrative transfer to H10W 72/076>
D	H01L2224/84385	4	Shape, e.g. interlocking features	<administrative transfer to H10W 72/076 and H10W 72/931 simultaneously>
D	H01L2224/84395	4	having an external coating, e.g. protective bond-through coating	<administrative transfer to H10W 72/076 and H10W 72/923 simultaneously>
D	H01L2224/84399	4	Material	<administrative transfer to H10W 72/076 and H10W 72/951 simultaneously>
D	H01L2224/844	5	with a principal constituent of the material being a metal or a metalloid, e.g. boron [B], silicon [Si], germanium [Ge], arsenic [As], antimony [Sb], tellurium [Te] and polonium [Po], and alloys thereof	<administrative transfer to H10W 72/076 and H10W 72/952 simultaneously>
D	H01L2224/84401	6	the principal constituent melting at a temperature of less than 400°C	<administrative transfer to H10W 72/076 and H10W 72/952 simultaneously>
D	H01L2224/84405	7	Gallium [Ga] as principal constituent	<administrative transfer to H10W 72/076 and H10W 72/952 simultaneously>
D	H01L2224/84409	7	Indium [In] as principal constituent	<administrative transfer to H10W 72/076 and H10W 72/952 simultaneously>
D	H01L2224/84411	7	Tin [Sn] as principal constituent	<administrative transfer to H10W 72/076 and H10W 72/952 simultaneously>
D	H01L2224/84413	7	Bismuth [Bi] as principal constituent	<administrative transfer to H10W 72/076 and H10W 72/952 simultaneously>
D	H01L2224/84414	7	Thallium [Tl] as principal constituent	<administrative transfer to H10W 72/076 and H10W 72/952 simultaneously>
D	H01L2224/84416	7	Lead [Pb] as principal constituent	<administrative transfer to H10W 72/076 and H10W 72/952 simultaneously>
D	H01L2224/84417	6	the principal constituent melting at a temperature of greater than or equal to 400°C and less than 950°C	<administrative transfer to H10W 72/076 and

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				H10W 72/952 simultaneously>
D	H01L2224/84418	7	Zinc [Zn] as principal constituent	<administrative transfer to H10W 72/076 and H10W 72/952 simultaneously>
D	H01L2224/8442	7	Antimony [Sb] as principal constituent	<administrative transfer to H10W 72/076 and H10W 72/952 simultaneously>
D	H01L2224/84423	7	Magnesium [Mg] as principal constituent	<administrative transfer to H10W 72/076 and H10W 72/952 simultaneously>
D	H01L2224/84424	7	Aluminium [Al] as principal constituent	<administrative transfer to H10W 72/076 and H10W 72/952 simultaneously>
D	H01L2224/84438	6	the principal constituent melting at a temperature of greater than or equal to 950°C and less than 1550°C	<administrative transfer to H10W 72/076 and H10W 72/952 simultaneously>
D	H01L2224/84439	7	Silver [Ag] as principal constituent	<administrative transfer to H10W 72/076 and H10W 72/952 simultaneously>
D	H01L2224/84444	7	Gold [Au] as principal constituent	<administrative transfer to H10W 72/076 and H10W 72/952 simultaneously>
D	H01L2224/84447	7	Copper [Cu] as principal constituent	<administrative transfer to H10W 72/076 and H10W 72/952 simultaneously>
D	H01L2224/84449	7	Manganese [Mn] as principal constituent	<administrative transfer to H10W 72/076 and H10W 72/952 simultaneously>
D	H01L2224/84455	7	Nickel [Ni] as principal constituent	<administrative transfer to H10W 72/076 and H10W 72/952 simultaneously>
D	H01L2224/84457	7	Cobalt [Co] as principal constituent	<administrative transfer to H10W 72/076 and H10W 72/952 simultaneously>
D	H01L2224/8446	7	Iron [Fe] as principal constituent	<administrative transfer to H10W 72/076 and H10W 72/952 simultaneously>

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D	H01L2224/84463	6	the principal constituent melting at a temperature of greater than 1550°C	<administrative transfer to H10W 72/076 and H10W 72/952 simultaneously>
D	H01L2224/84464	7	Palladium [Pd] as principal constituent	<administrative transfer to H10W 72/076 and H10W 72/952 simultaneously>
D	H01L2224/84466	7	Titanium [Ti] as principal constituent	<administrative transfer to H10W 72/076 and H10W 72/952 simultaneously>
D	H01L2224/84469	7	Platinum [Pt] as principal constituent	<administrative transfer to H10W 72/076 and H10W 72/952 simultaneously>
D	H01L2224/8447	7	Zirconium [Zr] as principal constituent	<administrative transfer to H10W 72/076 and H10W 72/952 simultaneously>
D	H01L2224/84471	7	Chromium [Cr] as principal constituent	<administrative transfer to H10W 72/076 and H10W 72/952 simultaneously>
D	H01L2224/84472	7	Vanadium [V] as principal constituent	<administrative transfer to H10W 72/076 and H10W 72/952 simultaneously>
D	H01L2224/84473	7	Rhodium [Rh] as principal constituent	<administrative transfer to H10W 72/076 and H10W 72/952 simultaneously>
D	H01L2224/84476	7	Ruthenium [Ru] as principal constituent	<administrative transfer to H10W 72/076 and H10W 72/952 simultaneously>
D	H01L2224/84478	7	Iridium [Ir] as principal constituent	<administrative transfer to H10W 72/076 and H10W 72/952 simultaneously>
D	H01L2224/84479	7	Niobium [Nb] as principal constituent	<administrative transfer to H10W 72/076 and H10W 72/952 simultaneously>
D	H01L2224/8448	7	Molybdenum [Mo] as principal constituent	<administrative transfer to H10W 72/076 and H10W 72/952 simultaneously>
D	H01L2224/84481	7	Tantalum [Ta] as principal constituent	<administrative transfer to H10W 72/076 and

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				H10W 72/952 simultaneously>
D	H01L2224/84483	7	Rhenium [Re] as principal constituent	<administrative transfer to H10W 72/076 and H10W 72/952 simultaneously>
D	H01L2224/84484	7	Tungsten [W] as principal constituent	<administrative transfer to H10W 72/076 and H10W 72/952 simultaneously>
D	H01L2224/84486	5	with a principal constituent of the material being a non metallic, non metalloid inorganic material	<administrative transfer to H10W 72/076 and H10W 72/953 simultaneously>
D	H01L2224/84487	6	Ceramics, e.g. crystalline carbides, nitrides or oxides	<administrative transfer to H10W 72/076 and H10W 72/953 simultaneously>
D	H01L2224/84488	6	Glasses, e.g. amorphous oxides, nitrides or fluorides	<administrative transfer to H10W 72/076 and H10W 72/953 simultaneously>
D	H01L2224/8449	5	with a principal constituent of the material being a polymer, e.g. polyester, phenolic based polymer, epoxy	<administrative transfer to H10W 72/076 and H10W 72/953 simultaneously>
D	H01L2224/84491	6	The principal constituent being an elastomer, e.g. silicones, isoprene, neoprene	<administrative transfer to H10W 72/076 and H10W 72/953 simultaneously>
D	H01L2224/84493	5	with a principal constituent of the material being a solid not provided for in groups H01L2224/844 - H01L2224/84491, e.g. allotropes of carbon, fullerene, graphite, carbon-nanotubes, diamond	<administrative transfer to H10W 72/076 and H10W 72/953 simultaneously>
D	H01L2224/84494	5	with a principal constituent of the material being a liquid not provided for in groups H01L2224/844 - H01L2224/84491	<administrative transfer to H10W 72/076 and H10W 72/953 simultaneously>
D	H01L2224/84495	5	with a principal constituent of the material being a gas not provided for in groups H01L2224/844 - H01L2224/84491	<administrative transfer to H10W 72/076 and H10W 72/953 simultaneously>
D	H01L2224/84498	5	with a principal constituent of the material being a combination of two or more materials in the form of a matrix with a filler, i.e. being a hybrid material, e.g. segmented structures, foams	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/951 simultaneously>
D	H01L2224/84499	6	Material of the matrix	<administrative transfer to H10W 72/076, H10W

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				72/925 and H10W 72/951 simultaneously>
D	H01L2224/845	7	with a principal constituent of the material being a metal or a metalloid, e.g. boron [B], silicon [Si], germanium [Ge], arsenic [As], antimony [Sb], tellurium [Te] and polonium [Po], and alloys thereof	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/84501	8	the principal constituent melting at a temperature of less than 400°C	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/84505	9	Gallium [Ga] as principal constituent	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/84509	9	Indium [In] as principal constituent	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/84511	9	Tin [Sn] as principal constituent	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/84513	9	Bismuth [Bi] as principal constituent	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/84514	9	Thallium [Tl] as principal constituent	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/84516	9	Lead [Pb] as principal constituent	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/84517	8	the principal constituent melting at a temperature of greater than or equal to 400°C and less than 950°C	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/84518	9	Zinc [Zn] as principal constituent	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/8452	9	Antimony [Sb] as principal constituent	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/84523	9	Magnesium [Mg] as principal constituent	<administrative transfer to H10W 72/076, H10W

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				72/925 and H10W 72/952 simultaneously>
D	H01L2224/84524	9	Aluminium [Al] as principal constituent	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/84538	8	the principal constituent melting at a temperature of greater than or equal to 950°C and less than 1550°C	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/84539	9	Silver [Ag] as principal constituent	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/84544	9	Gold [Au] as principal constituent	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/84547	9	Copper [Cu] as principal constituent	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/84549	9	Manganese [Mn] as principal constituent	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/84555	9	Nickel [Ni] as principal constituent	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/84557	9	Cobalt [Co] as principal constituent	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/8456	9	Iron [Fe] as principal constituent	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/84563	8	the principal constituent melting at a temperature of greater than 1550°C	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/84564	9	Palladium [Pd] as principal constituent	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/84566	9	Titanium [Ti] as principal constituent	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>

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D	H01L2224/84569	9	Platinum [Pt] as principal constituent	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/8457	9	Zirconium [Zr] as principal constituent	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/84571	9	Chromium [Cr] as principal constituent	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/84572	9	Vanadium [V] as principal constituent	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/84573	9	Rhodium [Rh] as principal constituent	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/84576	9	Ruthenium [Ru] as principal constituent	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/84578	9	Iridium [Ir] as principal constituent	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/84579	9	Niobium [Nb] as principal constituent	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/8458	9	Molybdenum [Mo] as principal constituent	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/84581	9	Tantalum [Ta] as principal constituent	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/84583	9	Rhenium [Re] as principal constituent	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/84584	9	Tungsten [W] as principal constituent	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>

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D	H01L2224/84586	7	with a principal constituent of the material being a non metallic, non metalloid inorganic material	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/953 simultaneously>
D	H01L2224/84587	8	Ceramics, e.g. crystalline carbides, nitrides or oxides	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/953 simultaneously>
D	H01L2224/84588	8	Glasses, e.g. amorphous oxides, nitrides or fluorides	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/953 simultaneously>
D	H01L2224/8459	7	with a principal constituent of the material being a polymer, e.g. polyester, phenolic based polymer, epoxy	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/953 simultaneously>
D	H01L2224/84591	8	The principal constituent being an elastomer, e.g. silicones, isoprene, neoprene	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/953 simultaneously>
D	H01L2224/84593	7	with a principal constituent of the material being a solid not provided for in groups H01L2224/845 - H01L2224/84591, e.g. allotropes of carbon, fullerene, graphite, carbon-nanotubes, diamond	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/953 simultaneously>
D	H01L2224/84594	7	with a principal constituent of the material being a liquid not provided for in groups H01L2224/845 - H01L2224/84591	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/953 simultaneously>
D	H01L2224/84595	7	with a principal constituent of the material being a gas not provided for in groups H01L2224/845 - H01L2224/84591	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/953 simultaneously>
D	H01L2224/84598	6	Fillers	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/951 simultaneously>
D	H01L2224/84599	7	Base material	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/951 simultaneously>
D	H01L2224/846	8	with a principal constituent of the material being a metal or a metalloid, e.g. boron [B], silicon [Si], germanium [Ge], arsenic [As], antimony [Sb], tellurium [Te] and polonium [Po], and alloys thereof	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/84601	9	the principal constituent melting at a temperature of less than 400°C	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>

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D	H01L2224/84605	10	Gallium [Ga] as principal constituent	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/84609	10	Indium [In] as principal constituent	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/84611	10	Tin [Sn] as principal constituent	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/84613	10	Bismuth [Bi] as principal constituent	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/84614	10	Thallium [Tl] as principal constituent	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/84616	10	Lead [Pb] as principal constituent	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/84617	9	the principal constituent melting at a temperature of greater than or equal to 400°C and less than 950°C	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/84618	10	Zinc [Zn] as principal constituent	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/8462	10	Antimony [Sb] as principal constituent	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/84623	10	Magnesium [Mg] as principal constituent	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/84624	10	Aluminium [Al] as principal constituent	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/84638	9	the principal constituent melting at a temperature of greater than or equal to 950°C and less than 1550°C	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/84639	10	Silver [Ag] as principal constituent	<administrative transfer to H10W 72/076, H10W

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				72/925 and H10W 72/952 simultaneously>
D	H01L2224/84644	10	Gold [Au] as principal constituent	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/84647	10	Copper [Cu] as principal constituent	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/84649	10	Manganese [Mn] as principal constituent	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/84655	10	Nickel [Ni] as principal constituent	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/84657	10	Cobalt [Co] as principal constituent	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/8466	10	Iron [Fe] as principal constituent	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/84663	9	the principal constituent melting at a temperature of greater than 1550°C	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/84664	10	Palladium [Pd] as principal constituent	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/84666	10	Titanium [Ti] as principal constituent	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/84669	10	Platinum [Pt] as principal constituent	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/8467	10	Zirconium [Zr] as principal constituent	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/84671	10	Chromium [Cr] as principal constituent	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>

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D	H01L2224/84672	10	Vanadium [V] as principal constituent	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/84673	10	Rhodium [Rh] as principal constituent	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/84676	10	Ruthenium [Ru] as principal constituent	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/84678	10	Iridium [Ir] as principal constituent	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/84679	10	Niobium [Nb] as principal constituent	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/8468	10	Molybdenum [Mo] as principal constituent	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/84681	10	Tantalum [Ta] as principal constituent	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/84683	10	Rhenium [Re] as principal constituent	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/84684	10	Tungsten [W] as principal constituent	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/84686	8	with a principal constituent of the material being a non metallic, non metalloid inorganic material	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/953 simultaneously>
D	H01L2224/84687	9	Ceramics, e.g. crystalline carbides, nitrides or oxides	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/953 simultaneously>
D	H01L2224/84688	9	Glasses, e.g. amorphous oxides, nitrides or fluorides	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/953 simultaneously>

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D	H01L2224/8469	8	with a principal constituent of the material being a polymer, e.g. polyester, phenolic based polymer, epoxy	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/953 simultaneously>
D	H01L2224/84691	9	The principal constituent being an elastomer, e.g. silicones, isoprene, neoprene	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/953 simultaneously>
D	H01L2224/84693	8	with a principal constituent of the material being a solid not provided for in groups H01L2224/846 - H01L2224/84691, e.g. allotropes of carbon, fullerene, graphite, carbon-nanotubes, diamond	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/953 simultaneously>
D	H01L2224/84694	8	with a principal constituent of the material being a liquid not provided for in groups H01L2224/846 - H01L2224/84691	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/953 simultaneously>
D	H01L2224/84695	8	with a principal constituent of the material being a gas not provided for in groups H01L2224/846 - H01L2224/84691	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/953 simultaneously>
D	H01L2224/84698	8	with a principal constituent of the material being a combination of two or more materials in the form of a matrix with a filler, i.e. being a hybrid material, e.g. segmented structures, foams	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/951 simultaneously>
D	H01L2224/84699	7	Coating material	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/951 simultaneously>
D	H01L2224/847	8	with a principal constituent of the material being a metal or a metalloid, e.g. boron [B], silicon [Si], germanium [Ge], arsenic [As], antimony [Sb], tellurium [Te] and polonium [Po], and alloys thereof	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/84701	9	the principal constituent melting at a temperature of less than 400°C	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/84705	10	Gallium [Ga] as principal constituent	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/84709	10	Indium [In] as principal constituent	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/84711	10	Tin [Sn] as principal constituent	<administrative transfer to H10W 72/076, H10W

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				72/925 and H10W 72/952 simultaneously>
D	H01L2224/84713	10	Bismuth [Bi] as principal constituent	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/84714	10	Thallium [Tl] as principal constituent	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/84716	10	Lead [Pb] as principal constituent	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/84717	9	the principal constituent melting at a temperature of greater than or equal to 400°C and less than 950°C	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/84718	10	Zinc [Zn] as principal constituent	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/8472	10	Antimony [Sb] as principal constituent	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/84723	10	Magnesium [Mg] as principal constituent	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/84724	10	Aluminium [Al] as principal constituent	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/84738	9	the principal constituent melting at a temperature of greater than or equal to 950°C and less than 1550°C	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/84739	10	Silver [Ag] as principal constituent	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/84744	10	Gold [Au] as principal constituent	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/84747	10	Copper [Cu] as principal constituent	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>

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D	H01L2224/84749	10	Manganese [Mn] as principal constituent	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/84755	10	Nickel [Ni] as principal constituent	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/84757	10	Cobalt [Co] as principal constituent	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/8476	10	Iron [Fe] as principal constituent	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/84763	9	the principal constituent melting at a temperature of greater than 1550°C	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/84764	10	Palladium [Pd] as principal constituent	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/84766	10	Titanium [Ti] as principal constituent	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/84769	10	Platinum [Pt] as principal constituent	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/8477	10	Zirconium [Zr] as principal constituent	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/84771	10	Chromium [Cr] as principal constituent	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/84772	10	Vanadium [V] as principal constituent	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/84773	10	Rhodium [Rh] as principal constituent	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/84776	10	Ruthenium [Ru] as principal constituent	<administrative transfer to H10W 72/076, H10W

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				72/925 and H10W 72/952 simultaneously>
D	H01L2224/84778	10	Iridium [Ir] as principal constituent	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/84779	10	Niobium [Nb] as principal constituent	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/8478	10	Molybdenum [Mo] as principal constituent	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/84781	10	Tantalum [Ta] as principal constituent	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/84783	10	Rhenium [Re] as principal constituent	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/84784	10	Tungsten [W] as principal constituent	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L2224/84786	8	with a principal constituent of the material being a non metallic, non metalloid inorganic material	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/953 simultaneously>
D	H01L2224/84787	9	Ceramics, e.g. crystalline carbides, nitrides or oxides	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/953 simultaneously>
D	H01L2224/84788	9	Glasses, e.g. amorphous oxides, nitrides or fluorides	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/953 simultaneously>
D	H01L2224/8479	8	with a principal constituent of the material being a polymer, e.g. polyester, phenolic based polymer, epoxy	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/953 simultaneously>
D	H01L2224/84791	9	The principal constituent being an elastomer, e.g. silicones, isoprene, neoprene	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/953 simultaneously>
D	H01L2224/84793	8	with a principal constituent of the material being a solid not provided for in groups H01L2224/847 - H01L2224/84791, e.g.	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/953 simultaneously>

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			allotropes of carbon, fullerene, graphite, carbon-nanotubes, diamond	
D	H01L2224/84794	8	with a principal constituent of the material being a liquid not provided for in groups H01L2224/847 - H01L2224/84791	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/953 simultaneously>
D	H01L2224/84795	8	with a principal constituent of the material being a gas not provided for in groups H01L2224/847 - H01L2224/84791	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/953 simultaneously>
D	H01L2224/84798	8	with a principal constituent of the material being a combination of two or more materials in the form of a matrix with a filler, i.e. being a hybrid material, e.g. segmented structures, foams	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/951 simultaneously>
D	H01L2224/84799	7	Shape or distribution of the fillers	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/951 simultaneously>
D	H01L2224/848	3	Bonding techniques	<administrative transfer to H10W 72/07631>
D	H01L2224/84801	4	Soldering or alloying	<administrative transfer to H10W 72/07636>
D	H01L2224/84805	5	involving forming a eutectic alloy at the bonding interface	<administrative transfer to H10W 72/07636 and H10W 72/07655 simultaneously>
D	H01L2224/8481	5	involving forming an intermetallic compound at the bonding interface	<administrative transfer to H10W 72/07636 and H10W 72/6528 simultaneously>
D	H01L2224/84815	5	Reflow soldering	<administrative transfer to H10W 72/07636>
D	H01L2224/8482	5	Diffusion bonding	<administrative transfer to H10W 72/07631>
D	H01L2224/84825	6	Solid-liquid interdiffusion	<administrative transfer to H10W 72/07631>
D	H01L2224/8483	6	Solid-solid interdiffusion	<administrative transfer to H10W 72/07631>
D	H01L2224/8484	4	Sintering	<administrative transfer to H10W 72/07631>
D	H01L2224/8485	4	using a polymer adhesive, e.g. an adhesive based on silicone, epoxy, polyimide, polyester	<administrative transfer to H10W 72/07637>
D	H01L2224/84855	5	Hardening the adhesive by curing, i.e. thermosetting	<administrative transfer to H10W 72/07637>
D	H01L2224/84856	6	Pre-cured adhesive, i.e. B-stage adhesive	<administrative transfer to H10W 72/07637>

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D	H01L2224/84859	6	Localised curing of parts of the connector	<administrative transfer to H10W 72/07637>
D	H01L2224/84862	6	Heat curing	<administrative transfer to H10W 72/07637>
D	H01L2224/84865	6	Microwave curing	<administrative transfer to H10W 72/07637>
D	H01L2224/84868	6	Infrared [IR] curing	<administrative transfer to H10W 72/07637>
D	H01L2224/84871	6	Visible light curing	<administrative transfer to H10W 72/07637>
D	H01L2224/84874	6	Ultraviolet [UV] curing	<administrative transfer to H10W 72/07637>
D	H01L2224/84877	6	Moisture curing, i.e. curing by exposing to humidity, e.g. for silicones and polyurethanes	<administrative transfer to H10W 72/07637>
D	H01L2224/8488	5	Hardening the adhesive by cooling, e.g. for thermoplastics or hot-melt adhesives	<administrative transfer to H10W 72/07637>
D	H01L2224/84885	5	Combinations of two or more hardening methods provided for in at least two different groups from H01L2224/84855 - H01L2224/8488, e.g. for hybrid thermoplastic-thermosetting adhesives	<administrative transfer to H10W 72/07637>
D	H01L2224/8489	4	using an inorganic non metallic glass type adhesive, e.g. solder glass	<administrative transfer to H10W 72/07631>
D	H01L2224/84893	4	Anodic bonding, i.e. bonding by applying a voltage across the interface in order to induce ions migration leading to an irreversible chemical bond	<administrative transfer to H10W 72/07631>
D	H01L2224/84895	4	Direct bonding, i.e. joining surfaces by means of intermolecular attracting interactions at their interfaces, e.g. covalent bonds, van der Waals forces	<administrative transfer to H10W 72/07631>
D	H01L2224/84897	5	between electrically conductive surfaces, e.g. copper-copper direct bonding, surface activated bonding	<administrative transfer to H10W 72/07631>
D	H01L2224/84898	5	between electrically insulating surfaces, e.g. oxide or nitride layers	<administrative transfer to H10W 72/07631>
D	H01L2224/84899	4	Combinations of bonding methods provided for in at least two different groups from H01L2224/848 - H01L2224/84898	<administrative transfer to H10W 72/07631>
D	H01L2224/849	3	involving monitoring, e.g. feedback loop	<administrative transfer to H10W 72/07631>
D	H01L2224/84909	3	Post-treatment of the connector or bonding area	<administrative transfer to H10W 72/076 and H10W 72/016 simultaneously>
D	H01L2224/8491	4	Cleaning, e.g. oxide removal step, desmearing	<administrative transfer to H10W 72/076 and H10W 72/01671 simultaneously>

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D	H01L2224/84911	5	Chemical cleaning, e.g. etching, flux	<administrative transfer to H10W 72/076 and H10W 72/01671 simultaneously>
D	H01L2224/84912	5	Mechanical cleaning, e.g. abrasion using hydro blasting, brushes, ultrasonic cleaning, dry ice blasting, gas-flow	<administrative transfer to H10W 72/076 and H10W 72/01671 simultaneously>
D	H01L2224/84913	5	Plasma cleaning	<administrative transfer to H10W 72/076 and H10W 72/01671 simultaneously>
D	H01L2224/84914	5	Thermal cleaning, e.g. using laser ablation or by electrostatic corona discharge	<administrative transfer to H10W 72/076 and H10W 72/01671 simultaneously>
D	H01L2224/84919	5	Combinations of two or more cleaning methods provided for in at least two different groups from H01L2224/8491 - H01L2224/84914	<administrative transfer to H10W 72/076 and H10W 72/01671 simultaneously>
D	H01L2224/8492	4	Applying permanent coating, e.g. protective coating	<administrative transfer to H10W 72/076 and H10W 72/01615 simultaneously>
D	H01L2224/8493	4	Reshaping, e.g. for severing the strap, modifying the loop shape	<administrative transfer to H10W 72/076 and H10W 72/01651 simultaneously>
D	H01L2224/84931	5	by chemical means, e.g. etching	<administrative transfer to H10W 72/076 and H10W 72/01653 simultaneously>
D	H01L2224/84935	5	by heating means, e.g. reflowing	<administrative transfer to H10W 72/076 and H10W 72/016 simultaneously>
D	H01L2224/84937	6	using a polychromatic heating lamp	<administrative transfer to H10W 72/076 and H10W 72/016 simultaneously>
D	H01L2224/84939	6	using a laser	<administrative transfer to H10W 72/076 and H10W 72/016 simultaneously>
D	H01L2224/84941	6	Induction heating, i.e. eddy currents	<administrative transfer to H10W 72/076 and H10W 72/016 simultaneously>
D	H01L2224/84943	6	using a flame torch, e.g. hydrogen torch	<administrative transfer to H10W 72/076 and

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				H10W 72/016 simultaneously>
D	H01L2224/84945	6	using a corona discharge, e.g. electronic flame off [EFO]	<administrative transfer to H10W 72/076 and H10W 72/016 simultaneously>
D	H01L2224/84947	5	by mechanical means, e.g. pressing, stamping	<administrative transfer to H10W 72/076 and H10W 72/01661 simultaneously>
D	H01L2224/84948	4	Thermal treatments, e.g. annealing, controlled cooling	<administrative transfer to H10W 72/076 and H10W 72/016 simultaneously>
D	H01L2224/84951	4	Forming additional members, e.g. for reinforcing	<administrative transfer to H10W 72/076 and H10W 72/016 simultaneously>
D	H01L2224/84986	3	Specific sequence of steps, e.g. repetition of manufacturing steps, time sequence	<administrative transfer to H10W 72/076>
D	H01L2224/85	2	using a wire connector	<administrative transfer to H10W 72/075>
D	H01L2224/85001	3	involving a temporary auxiliary member not forming part of the bonding apparatus, e.g. removable or sacrificial coating, film or substrate	<administrative transfer to H10W 72/07504>
D	H01L2224/85002	4	being a removable or sacrificial coating	<administrative transfer to H10W 72/07504>
D	H01L2224/85005	4	being a temporary or sacrificial substrate	<administrative transfer to H10W 72/07507>
D	H01L2224/85007	3	involving a permanent auxiliary member being left in the finished device, e.g. aids for holding or protecting the wire connector during or after the bonding process	<administrative transfer to H10W 72/07502>
D	H01L2224/85009	3	Pre-treatment of the connector or the bonding area	<administrative transfer to H10W 72/07511 and H10W 72/015 simultaneously>
D	H01L2224/8501	4	Cleaning, e.g. oxide removal step, desmearing	<administrative transfer to H10W 72/07511 and H10W 72/01571 simultaneously>
D	H01L2224/85011	5	Chemical cleaning, e.g. etching, flux	<administrative transfer to H10W 72/07511 and H10W 72/01571 simultaneously>
D	H01L2224/85012	5	Mechanical cleaning, e.g. abrasion using hydro blasting, brushes, ultrasonic cleaning, dry ice blasting, gas-flow	<administrative transfer to H10W 72/07511 and H10W 72/01571 simultaneously>

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D	H01L2224/85013	5	Plasma cleaning	<administrative transfer to H10W 72/07511 and H10W 72/01571 simultaneously>
D	H01L2224/85014	5	Thermal cleaning, e.g. decomposition, sublimation	<administrative transfer to H10W 72/07511 and H10W 72/01571 simultaneously>
D	H01L2224/85016	6	using a laser	<administrative transfer to H10W 72/07511 and H10W 72/01571 simultaneously>
D	H01L2224/85017	5	Electron beam cleaning	<administrative transfer to H10W 72/07511 and H10W 72/01571 simultaneously>
D	H01L2224/85019	5	Combinations of two or more cleaning methods provided for in at least two different groups from H01L2224/8501 - H01L2224/85014	<administrative transfer to H10W 72/07511 and H10W 72/01571 simultaneously>
D	H01L2224/8502	4	Applying permanent coating, e.g. in-situ coating	<administrative transfer to H10W 72/07511 and H10W 72/01515 simultaneously>
D	H01L2224/8503	4	Reshaping, e.g. forming the ball or the wedge of the wire connector	<administrative transfer to H10W 72/07511 and H10W 72/01551 simultaneously>
D	H01L2224/85031	5	by chemical means, e.g. etching, anodisation	<administrative transfer to H10W 72/07511 and H10W 72/01553 simultaneously>
D	H01L2224/85035	5	by heating means, e.g. "free-air-ball"	<administrative transfer to H10W 72/07511 and H10W 72/01551 simultaneously>
D	H01L2224/85037	6	using a polychromatic heating lamp	<administrative transfer to H10W 72/07511 and H10W 72/01551 simultaneously>
D	H01L2224/85039	6	using a laser	<administrative transfer to H10W 72/07511 and H10W 72/01551 simultaneously>
D	H01L2224/85041	6	Induction heating, i.e. eddy currents	<administrative transfer to H10W 72/07511 and H10W 72/01551 simultaneously>
D	H01L2224/85043	6	using a flame torch, e.g. hydrogen torch	<administrative transfer to H10W 72/07511 and

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				H10W 72/01551 simultaneously>
D	H01L2224/85045	6	using a corona discharge, e.g. electronic flame off [EFO]	<administrative transfer to H10W 72/07511 and H10W 72/01551 simultaneously>
D	H01L2224/85047	5	by mechanical means, e.g. severing, pressing, stamping	<administrative transfer to H10W 72/07511 and H10W 72/01551 simultaneously>
D	H01L2224/85048	4	Thermal treatments, e.g. annealing, controlled pre-heating or pre-cooling	<administrative transfer to H10W 72/07511>
D	H01L2224/85051	4	Forming additional members, e.g. for "wedge-on-ball", "ball-on-wedge", "ball-on- ball" connections	<administrative transfer to H10W 72/07511>
D	H01L2224/85053	3	Bonding environment	<administrative transfer to H10W 72/07541>
D	H01L2224/85054	4	Composition of the atmosphere	<administrative transfer to H10W 72/07541>
D	H01L2224/85055	5	being oxidating	<administrative transfer to H10W 72/07541>
D	H01L2224/85065	5	being reducing	<administrative transfer to H10W 72/07541>
D	H01L2224/85075	5	being inert	<administrative transfer to H10W 72/07541>
D	H01L2224/85085	4	being a liquid, e.g. for fluidic self-assembly	<administrative transfer to H10W 72/07541>
D	H01L2224/8509	4	Vacuum	<administrative transfer to H10W 72/07541>
D	H01L2224/85091	4	Under pressure	<administrative transfer to H10W 72/07541>
D	H01L2224/85092	5	Atmospheric pressure	<administrative transfer to H10W 72/07541>
D	H01L2224/85093	5	Transient conditions, e.g. gas-flow	<administrative transfer to H10W 72/07541>
D	H01L2224/85095	4	Temperature settings	<administrative transfer to H10W 72/07541>
D	H01L2224/85096	5	Transient conditions	<administrative transfer to H10W 72/07541>
D	H01L2224/85097	6	Heating	<administrative transfer to H10W 72/07541>
D	H01L2224/85098	6	Cooling	<administrative transfer to H10W 72/07541>
D	H01L2224/85099	5	Ambient temperature	<administrative transfer to H10W 72/07541>
D	H01L2224/851	3	the connector being supplied to the parts to be connected in the bonding apparatus	<administrative transfer to H10W 72/07502>

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D	H01L2224/8511	3	involving protection against electrical discharge, e.g. removing electrostatic charge	<administrative transfer to H10W 72/07502>
D	H01L2224/8512	3	Aligning	<administrative transfer to H10W 72/07521>
D	H01L2224/85121	4	Active alignment, i.e. by apparatus steering, e.g. optical alignment using marks or sensors	<administrative transfer to H10W 72/07523>
D	H01L2224/85122	5	by detecting inherent features of, or outside, the semiconductor or solid-state body	<administrative transfer to H10W 72/07523>
D	H01L2224/85123	6	Shape or position of the body	<administrative transfer to H10W 72/07523>
D	H01L2224/85125	6	Bonding areas on the body	<administrative transfer to H10W 72/07523>
D	H01L2224/85127	6	Bonding areas outside the body	<administrative transfer to H10W 72/07523>
D	H01L2224/85129	6	Shape or position of the other item	<administrative transfer to H10W 72/07523>
D	H01L2224/8513	5	using marks formed on the semiconductor or solid-state body	<administrative transfer to H10W 72/07523>
D	H01L2224/85132	5	using marks formed outside the semiconductor or solid-state body, i.e. "off-chip"	<administrative transfer to H10W 72/07523>
D	H01L2224/85136	4	involving guiding structures, e.g. spacers or supporting members	<administrative transfer to H10W 72/07527>
D	H01L2224/85138	5	the guiding structures being at least partially left in the finished device	<administrative transfer to H10W 72/07527>
D	H01L2224/85143	4	Passive alignment, i.e. self alignment, e.g. using surface energy, chemical reactions, thermal equilibrium	<administrative transfer to H10W 72/07521>
D	H01L2224/85148	4	involving movement of a part of the bonding apparatus	<administrative transfer to H10W 72/07521>
D	H01L2224/85149	5	being the lower part of the bonding apparatus, i.e. holding means for the bodies to be connected, e.g. XY table	<administrative transfer to H10W 72/07521>
D	H01L2224/8515	6	Rotational movements	<administrative transfer to H10W 72/07521>
D	H01L2224/8516	6	Translational movements	<administrative transfer to H10W 72/07521>
D	H01L2224/85169	5	being the upper part of the bonding apparatus, i.e. bonding head, e.g. capillary or wedge	<administrative transfer to H10W 72/07521>
D	H01L2224/8517	6	Rotational movements	<administrative transfer to H10W 72/07521>
D	H01L2224/8518	6	Translational movements	<administrative transfer to H10W 72/07521>
D	H01L2224/85181	7	connecting first on the semiconductor or solid-state body, i.e. on-chip, regular stitch	<administrative transfer to H10W 72/07521>
D	H01L2224/85186	7	connecting first outside the semiconductor or solid-state body, i.e. off-chip, reverse stitch	<administrative transfer to H10W 72/07521>

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D	H01L2224/85191	7	connecting first both on and outside the semiconductor or solid-state body, i.e. regular and reverse stitches	<administrative transfer to H10W 72/07521>
D	H01L2224/85196	7	involving intermediate connecting steps before cutting the wire connector	<administrative transfer to H10W 72/07521>
D	H01L2224/852	3	Applying energy for connecting	<administrative transfer to H10W 72/07531>
D	H01L2224/85201	4	Compression bonding	<administrative transfer to H10W 72/07532>
D	H01L2224/85203	5	Thermocompression bonding	<administrative transfer to H10W 72/07532>
D	H01L2224/85205	5	Ultrasonic bonding	<administrative transfer to H10W 72/07533>
D	H01L2224/85206	6	Direction of oscillation	<administrative transfer to H10W 72/07533>
D	H01L2224/85207	6	Thermosonic bonding	<administrative transfer to H10W 72/07533>
D	H01L2224/8521	4	with energy being in the form of electromagnetic radiation	<administrative transfer to H10W 72/07535>
D	H01L2224/85212	5	Induction heating, i.e. eddy currents	<administrative transfer to H10W 72/07535>
D	H01L2224/85214	5	using a laser	<administrative transfer to H10W 72/07535>
D	H01L2224/8523	5	Polychromatic or infrared lamp heating	<administrative transfer to H10W 72/07535>
D	H01L2224/85232	4	using an autocatalytic reaction, e.g. exothermic brazing	<administrative transfer to H10W 72/07531>
D	H01L2224/85234	4	using means for applying energy being within the device, e.g. integrated heater	<administrative transfer to H10W 72/07531>
D	H01L2224/85236	4	using electro-static corona discharge	<administrative transfer to H10W 72/07531>
D	H01L2224/85237	4	using electron beam	<administrative transfer to H10W 72/07531>
D	H01L2224/85238	4	using electric resistance welding, i.e. ohmic heating	<administrative transfer to H10W 72/07531>
D	H01L2224/8534	3	Bonding interfaces of the connector	<administrative transfer to H10W 72/075>
D	H01L2224/85345	4	Shape, e.g. interlocking features	<administrative transfer to H10W 72/075 and H10W 72/531 simultaneously>
D	H01L2224/85355	4	having an external coating, e.g. protective bond-through coating	<administrative transfer to H10W 72/075 and H10W 72/332 simultaneously>
D	H01L2224/85359	4	Material	<administrative transfer to H10W 72/075 and

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				H10W 72/551 simultaneously>
D	H01L2224/8536	3	Bonding interfaces of the semiconductor or solid state body	<administrative transfer to H10W 72/075 and H10W 72/90 simultaneously>
D	H01L2224/85365	4	Shape, e.g. interlocking features	<administrative transfer to H10W 72/075 and H10W 72/931 simultaneously>
D	H01L2224/85375	4	having an external coating, e.g. protective bond-through coating	<administrative transfer to H10W 72/075 and H10W 72/923 simultaneously>
D	H01L2224/85379	4	Material	<administrative transfer to H10W 72/075 and H10W 72/951 simultaneously>
D	H01L2224/8538	3	Bonding interfaces outside the semiconductor or solid-state body	<administrative transfer to H10W 72/075 and H10W 72/90 simultaneously>
D	H01L2224/85385	4	Shape, e.g. interlocking features	<administrative transfer to H10W 72/075 and H10W 72/931 simultaneously>
D	H01L2224/85395	4	having an external coating, e.g. protective bond-through coating	<administrative transfer to H10W 72/075 and H10W 72/923 simultaneously>
D	H01L2224/85399	4	Material	<administrative transfer to H10W 72/075 and H10W 72/951 simultaneously>
D	H01L2224/854	5	with a principal constituent of the material being a metal or a metalloid, e.g. boron (B), silicon (Si), germanium (Ge), arsenic (As), antimony (Sb), tellurium (Te) and polonium (Po), and alloys thereof	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85401	6	the principal constituent melting at a temperature of less than 400°C	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85405	7	Gallium (Ga) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85409	7	Indium (In) as principal constituent	<administrative transfer to H10W 72/075 and

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				H10W 72/952 simultaneously>
D	H01L2224/85411	7	Tin (Sn) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85413	7	Bismuth (Bi) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85414	7	Thallium (Tl) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85416	7	Lead (Pb) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85417	6	the principal constituent melting at a temperature of greater than or equal to 400°C and less than 950°C	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85418	7	Zinc (Zn) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/8542	7	Antimony (Sb) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85423	7	Magnesium (Mg) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85424	7	Aluminium (Al) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85438	6	the principal constituent melting at a temperature of greater than or equal to 950°C and less than 1550°C	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85439	7	Silver (Ag) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85444	7	Gold (Au) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>

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D	H01L2224/85447	7	Copper (Cu) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85449	7	Manganese (Mn) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85455	7	Nickel (Ni) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85457	7	Cobalt (Co) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/8546	7	Iron (Fe) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85463	6	the principal constituent melting at a temperature of greater than 1550°C	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85464	7	Palladium (Pd) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85466	7	Titanium (Ti) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85469	7	Platinum (Pt) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/8547	7	Zirconium (Zr) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85471	7	Chromium (Cr) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85472	7	Vanadium (V) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85473	7	Rhodium (Rh) as principal constituent	<administrative transfer to H10W 72/075 and

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				H10W 72/952 simultaneously>
D	H01L2224/85476	7	Ruthenium (Ru) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85478	7	Iridium (Ir) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85479	7	Niobium (Nb) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/8548	7	Molybdenum (Mo) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85481	7	Tantalum (Ta) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85483	7	Rhenium (Re) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85484	7	Tungsten (W) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85486	5	with a principal constituent of the material being a non metallic, non metalloid inorganic material	<administrative transfer to H10W 72/075 and H10W 72/953 simultaneously>
D	H01L2224/85487	6	Ceramics, e.g. crystalline carbides, nitrides or oxides	<administrative transfer to H10W 72/075 and H10W 72/953 simultaneously>
D	H01L2224/85488	6	Glasses, e.g. amorphous oxides, nitrides or fluorides	<administrative transfer to H10W 72/075 and H10W 72/953 simultaneously>
D	H01L2224/8549	5	with a principal constituent of the material being a polymer, e.g. polyester, phenolic based polymer, epoxy	<administrative transfer to H10W 72/075 and H10W 72/953 simultaneously>
D	H01L2224/85491	6	The principal constituent being an elastomer, e.g. silicones, isoprene, neoprene	<administrative transfer to H10W 72/075 and H10W 72/953 simultaneously>

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D	H01L2224/85493	5	with a principal constituent of the material being a solid not provided for in groups H01L2224/854 - H01L2224/85491, e.g. allotropes of carbon, fullerene, graphite, carbon-nanotubes, diamond	<administrative transfer to H10W 72/075 and H10W 72/953 simultaneously>
D	H01L2224/85494	5	with a principal constituent of the material being a liquid not provided for in groups H01L2224/854 - H01L2224/85491	<administrative transfer to H10W 72/075 and H10W 72/953 simultaneously>
D	H01L2224/85495	5	with a principal constituent of the material being a gas not provided for in groups H01L2224/854 - H01L2224/85491	<administrative transfer to H10W 72/075 and H10W 72/953 simultaneously>
D	H01L2224/85498	5	with a principal constituent of the material being a combination of two or more materials in the form of a matrix with a filler, i.e. being a hybrid material, e.g. segmented structures, foams	<administrative transfer to H10W 72/075 and H10W 72/951 simultaneously>
D	H01L2224/85499	6	Material of the matrix	<administrative transfer to H10W 72/075 and H10W 72/951 simultaneously>
D	H01L2224/855	7	with a principal constituent of the material being a metal or a metalloid, e.g. boron (B), silicon (Si), germanium (Ge), arsenic (As), antimony (Sb), tellurium (Te) and polonium (Po), and alloys thereof	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85501	8	the principal constituent melting at a temperature of less than 400°C	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85505	9	Gallium (Ga) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85509	9	Indium (In) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85511	9	Tin (Sn) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85513	9	Bismuth (Bi) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85514	9	Thallium (Tl) as principal constituent	<administrative transfer to H10W 72/075 and

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				H10W 72/952 simultaneously>
D	H01L2224/85516	9	Lead (Pb) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85517	8	the principal constituent melting at a temperature of greater than or equal to 400°C and less than 950°C	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85518	9	Zinc (Zn) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/8552	9	Antimony (Sb) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85523	9	Magnesium (Mg) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85524	9	Aluminium (Al) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85538	8	the principal constituent melting at a temperature of greater than or equal to 950°C and less than 1550°C	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85539	9	Silver (Ag) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85544	9	Gold (Au) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85547	9	Copper (Cu) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85549	9	Manganese (Mn) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85555	9	Nickel (Ni) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>

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D	H01L2224/85557	9	Cobalt (Co) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85556	9	Iron (Fe) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85563	8	the principal constituent melting at a temperature of greater than 1550°C	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85564	9	Palladium (Pd) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85566	9	Titanium (Ti) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85569	9	Platinum (Pt) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85557	9	Zirconium (Zr) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85571	9	Chromium (Cr) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85572	9	Vanadium (V) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85573	9	Rhodium (Rh) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85576	9	Ruthenium (Ru) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85578	9	Iridium (Ir) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85579	9	Niobium (Nb) as principal constituent	<administrative transfer to H10W 72/075 and

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				H10W 72/952 simultaneously>
D	H01L2224/8558	9	Molybdenum (Mo) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85581	9	Tantalum (Ta) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85583	9	Rhenium (Re) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85584	9	Tungsten (W) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85586	7	with a principal constituent of the material being a non metallic, non metalloid inorganic material	<administrative transfer to H10W 72/075 and H10W 72/953 simultaneously>
D	H01L2224/85587	8	Ceramics, e.g. crystalline carbides, nitrides or oxides	<administrative transfer to H10W 72/075 and H10W 72/953 simultaneously>
D	H01L2224/85588	8	Glasses, e.g. amorphous oxides, nitrides or fluorides	<administrative transfer to H10W 72/075 and H10W 72/953 simultaneously>
D	H01L2224/8559	7	with a principal constituent of the material being a polymer, e.g. polyester, phenolic based polymer, epoxy	<administrative transfer to H10W 72/075 and H10W 72/953 simultaneously>
D	H01L2224/85591	8	The principal constituent being an elastomer, e.g. silicones, isoprene, neoprene	<administrative transfer to H10W 72/075 and H10W 72/953 simultaneously>
D	H01L2224/85593	7	with a principal constituent of the material being a solid not provided for in groups H01L2224/855 - H01L2224/85591, e.g. allotropes of carbon, fullerene, graphite, carbon-nanotubes, diamond	<administrative transfer to H10W 72/075 and H10W 72/953 simultaneously>
D	H01L2224/85594	7	with a principal constituent of the material being a liquid not provided for in groups H01L2224/855 - H01L2224/85591	<administrative transfer to H10W 72/075 and H10W 72/953 simultaneously>
D	H01L2224/85595	7	with a principal constituent of the material being a gas not provided for in groups H01L2224/855 - H01L2224/85591	<administrative transfer to H10W 72/075 and

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				H10W 72/953 simultaneously>
D	H01L2224/85598	6	Fillers	<administrative transfer to H10W 72/075 and H10W 72/951 simultaneously>
D	H01L2224/85599	7	Base material	<administrative transfer to H10W 72/075 and H10W 72/951 simultaneously>
D	H01L2224/856	8	with a principal constituent of the material being a metal or a metalloid, e.g. boron (B), silicon (Si), germanium (Ge), arsenic (As), antimony (Sb), tellurium (Te) and polonium (Po), and alloys thereof	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85601	9	the principal constituent melting at a temperature of less than 400°C	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85605	10	Gallium (Ga) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85609	10	Indium (In) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85611	10	Tin (Sn) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85613	10	Bismuth (Bi) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85614	10	Thallium (Tl) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85616	10	Lead (Pb) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85617	9	the principal constituent melting at a temperature of greater than or equal to 400°C and less than 950°C	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85618	10	Zinc (Zn) as principal constituent	<administrative transfer to H10W 72/075 and

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				H10W 72/952 simultaneously>
D	H01L2224/8562	10	Antimony (Sb) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85623	10	Magnesium (Mg) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85624	10	Aluminium (Al) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85638	9	the principal constituent melting at a temperature of greater than or equal to 950°C and less than 1550°C	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85639	10	Silver (Ag) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85644	10	Gold (Au) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85647	10	Copper (Cu) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85649	10	Manganese (Mn) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85655	10	Nickel (Ni) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85657	10	Cobalt (Co) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/8566	10	Iron (Fe) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85663	9	the principal constituent melting at a temperature of greater than 1550°C	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>

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D	H01L2224/85664	10	Palladium (Pd) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85666	10	Titanium (Ti) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85669	10	Platinum (Pt) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/8567	10	Zirconium (Zr) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85671	10	Chromium (Cr) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85672	10	Vanadium (V) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85673	10	Rhodium (Rh) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85676	10	Ruthenium (Ru) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85678	10	Iridium (Ir) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85679	10	Niobium (Nb) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/8568	10	Molybdenum (Mo) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85681	10	Tantalum (Ta) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85683	10	Rhenium (Re) as principal constituent	<administrative transfer to H10W 72/075 and

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				H10W 72/952 simultaneously>
D	H01L2224/85684	10	Tungsten (W) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85686	8	with a principal constituent of the material being a non metallic, non metalloid inorganic material	<administrative transfer to H10W 72/075 and H10W 72/953 simultaneously>
D	H01L2224/85687	9	Ceramics, e.g. crystalline carbides, nitrides or oxides	<administrative transfer to H10W 72/075 and H10W 72/953 simultaneously>
D	H01L2224/85688	9	Glasses, e.g. amorphous oxides, nitrides or fluorides	<administrative transfer to H10W 72/075 and H10W 72/953 simultaneously>
D	H01L2224/8569	8	with a principal constituent of the material being a polymer, e.g. polyester, phenolic based polymer, epoxy	<administrative transfer to H10W 72/075 and H10W 72/953 simultaneously>
D	H01L2224/85691	9	The principal constituent being an elastomer, e.g. silicones, isoprene, neoprene	<administrative transfer to H10W 72/075 and H10W 72/953 simultaneously>
D	H01L2224/85693	8	with a principal constituent of the material being a solid not provided for in groups H01L2224/856 - H01L2224/85691, e.g. allotropes of carbon, fullerene, graphite, carbon-nanotubes, diamond	<administrative transfer to H10W 72/075 and H10W 72/953 simultaneously>
D	H01L2224/85694	8	with a principal constituent of the material being a liquid not provided for in groups H01L2224/856 - H01L2224/85691	<administrative transfer to H10W 72/075 and H10W 72/953 simultaneously>
D	H01L2224/85695	8	with a principal constituent of the material being a gas not provided for in groups H01L2224/856 - H01L2224/85691	<administrative transfer to H10W 72/075 and H10W 72/953 simultaneously>
D	H01L2224/85698	8	with a principal constituent of the material being a combination of two or more materials in the form of a matrix with a filler, i.e. being a hybrid material, e.g. segmented structures, foams	<administrative transfer to H10W 72/075 and H10W 72/951 simultaneously>
D	H01L2224/85699	7	Coating material	<administrative transfer to H10W 72/075 and H10W 72/951 simultaneously>
D	H01L2224/857	8	with a principal constituent of the material being a metal or a metalloid, e.g. boron (B)	<administrative transfer to H10W 72/075 and

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			silicon (Si), germanium (Ge), arsenic (As), antimony (Sb), tellurium (Te) and polonium (Po), and alloys thereof	H10W 72/952 simultaneously>
D	H01L2224/85701	9	the principal constituent melting at a temperature of less than 400°C	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85705	10	Gallium (Ga) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85709	10	Indium (In) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85711	10	Tin (Sn) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85713	10	Bismuth (Bi) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85714	10	Thallium (Tl) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85716	10	Lead (Pb) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85717	9	the principal constituent melting at a temperature of greater than or equal to 400°C and less than 950°C	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85718	10	Zinc (Zn) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/8572	10	Antimony (Sb) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85723	10	Magnesium (Mg) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85724	10	Aluminium (Al) as principal constituent	<administrative transfer to H10W 72/075 and

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				H10W 72/952 simultaneously>
D	H01L2224/85738	9	the principal constituent melting at a temperature of greater than or equal to 950°C and less than 1550°C	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85739	10	Silver (Ag) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85744	10	Gold (Au) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85747	10	Copper (Cu) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85749	10	Manganese (Mn) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85755	10	Nickel (Ni) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85757	10	Cobalt (Co) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/8576	10	Iron (Fe) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85763	9	the principal constituent melting at a temperature of greater than 1550°C	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85764	10	Palladium (Pd) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85766	10	Titanium (Ti) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85769	10	Platinum (Pt) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>

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D	H01L2224/8577	10	Zirconium (Zr) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85771	10	Chromium (Cr) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85772	10	Vanadium (V) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85773	10	Rhodium (Rh) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85776	10	Ruthenium (Ru) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85778	10	Iridium (Ir) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85779	10	Niobium (Nb) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/8578	10	Molybdenum (Mo) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85781	10	Tantalum (Ta) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85783	10	Rhenium (Re) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85784	10	Tungsten (W) as principal constituent	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L2224/85786	8	with a principal constituent of the material being a non metallic, non metalloid inorganic material	<administrative transfer to H10W 72/075 and H10W 72/953 simultaneously>
D	H01L2224/85787	9	Ceramics, e.g. crystalline carbides, nitrides or oxides	<administrative transfer to H10W 72/075 and

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				H10W 72/953 simultaneously>
D	H01L2224/85788	9	Glasses, e.g. amorphous oxides, nitrides or fluorides	<administrative transfer to H10W 72/075 and H10W 72/953 simultaneously>
D	H01L2224/8579	8	with a principal constituent of the material being a polymer, e.g. polyester, phenolic based polymer, epoxy	<administrative transfer to H10W 72/075 and H10W 72/953 simultaneously>
D	H01L2224/85791	9	The principal constituent being an elastomer, e.g. silicones, isoprene, neoprene	<administrative transfer to H10W 72/075 and H10W 72/953 simultaneously>
D	H01L2224/85793	8	with a principal constituent of the material being a solid not provided for in groups H01L2224/857 - H01L2224/85791, e.g. allotropes of carbon, fullerene, graphite, carbon-nanotubes, diamond	<administrative transfer to H10W 72/075 and H10W 72/953 simultaneously>
D	H01L2224/85794	8	with a principal constituent of the material being a liquid not provided for in groups H01L2224/857 - H01L2224/85791	<administrative transfer to H10W 72/075 and H10W 72/953 simultaneously>
D	H01L2224/85795	8	with a principal constituent of the material being a gas not provided for in groups H01L2224/857 - H01L2224/85791	<administrative transfer to H10W 72/075 and H10W 72/953 simultaneously>
D	H01L2224/85798	8	with a principal constituent of the material being a combination of two or more materials in the form of a matrix with a filler, i.e. being a hybrid material, e.g. segmented structures, foams	<administrative transfer to H10W 72/075 and H10W 72/951 simultaneously>
D	H01L2224/85799	6	Shape or distribution of the fillers	<administrative transfer to H10W 72/075 and H10W 72/951 simultaneously>
D	H01L2224/858	3	Bonding techniques	<administrative transfer to H10W 72/07531>
D	H01L2224/85801	4	Soldering or alloying	<administrative transfer to H10W 72/07536>
D	H01L2224/85805	5	involving forming a eutectic alloy at the bonding interface	<administrative transfer to H10W 72/07536>
D	H01L2224/8581	5	involving forming an intermetallic compound at the bonding interface	<administrative transfer to H10W 72/07536>
D	H01L2224/85815	5	Reflow soldering	<administrative transfer to H10W 72/07536>
D	H01L2224/8582	5	Diffusion bonding	<administrative transfer to H10W 72/07536>
D	H01L2224/85825	6	Solid-liquid interdiffusion	<administrative transfer to H10W 72/07536>

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D	H01L2224/8583	6	Solid-solid interdiffusion, e.g. "direct bonding"	<administrative transfer to H10W 72/07536>
D	H01L2224/8584	4	Sintering	<administrative transfer to H10W 72/07531>
D	H01L2224/8585	4	using a polymer adhesive, e.g. an adhesive based on silicone, epoxy, polyimide, polyester	<administrative transfer to H10W 72/07537>
D	H01L2224/85855	5	Hardening the adhesive by curing, i.e. thermosetting	<administrative transfer to H10W 72/07537>
D	H01L2224/85856	6	Pre-cured adhesive, i.e. B-stage adhesive	<administrative transfer to H10W 72/07537>
D	H01L2224/85859	6	Localised curing of parts of the connector	<administrative transfer to H10W 72/07537>
D	H01L2224/85862	6	Heat curing	<administrative transfer to H10W 72/07537>
D	H01L2224/85865	6	Microwave curing	<administrative transfer to H10W 72/07537>
D	H01L2224/85868	6	Infrared [IR] curing	<administrative transfer to H10W 72/07537>
D	H01L2224/85871	6	Visible light curing	<administrative transfer to H10W 72/07537>
D	H01L2224/85874	6	Ultraviolet [UV] curing	<administrative transfer to H10W 72/07537>
D	H01L2224/85877	6	Moisture curing, i.e. curing by exposing to humidity, e.g. for silicones and polyurethanes	<administrative transfer to H10W 72/07537>
D	H01L2224/8588	5	Hardening the adhesive by cooling, e.g. for thermoplastics or hot-melt adhesives	<administrative transfer to H10W 72/07537>
D	H01L2224/85885	5	Combinations of two or more hardening methods provided for in at least two different groups from H01L2224/85855 - H01L2224/8588, e.g. for hybrid thermoplastic-thermosetting adhesives	<administrative transfer to H10W 72/07537>
D	H01L2224/8589	4	using an inorganic non metallic glass type adhesive, e.g. solder glass	<administrative transfer to H10W 72/07531>
D	H01L2224/85893	4	Anodic bonding, i.e. bonding by applying a voltage across the interface in order to induce ions migration leading to an irreversible chemical bond	<administrative transfer to H10W 72/07531>
D	H01L2224/85895	4	Direct bonding, i.e. joining surfaces by means of intermolecular attracting interactions at their interfaces, e.g. covalent bonds, van der Waals forces	<administrative transfer to H10W 80/301>
D	H01L2224/85897	5	between electrically conductive surfaces, e.g. copper-copper direct bonding, surface activated bonding	<administrative transfer to H10W 80/314>
D	H01L2224/85898	5	between electrically insulating surfaces, e.g. oxide or nitride layers	<administrative transfer to H10W 80/327>

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D	H01L2224/85899	4	Combinations of bonding methods provided for in at least two different groups from H01L2224/858 - H01L2224/85898	<administrative transfer to H10W 72/07531>
D	H01L2224/859	3	involving monitoring, e.g. feedback loop	<administrative transfer to H10W 72/07531>
D	H01L2224/85909	3	Post-treatment of the connector or wire bonding area	<administrative transfer to H10W 72/075 and H10W 72/015 simultaneously>
D	H01L2224/8591	4	Cleaning, e.g. oxide removal step, desmearing	<administrative transfer to H10W 72/075 and H10W 72/01571 simultaneously>
D	H01L2224/85911	5	Chemical cleaning, e.g. etching, flux	<administrative transfer to H10W 72/075 and H10W 72/01571 simultaneously>
D	H01L2224/85912	5	Mechanical cleaning, e.g. abrasion using hydro blasting, brushes, ultrasonic cleaning, dry ice blasting, gas-flow	<administrative transfer to H10W 72/075 and H10W 72/01571 simultaneously>
D	H01L2224/85913	5	Plasma cleaning	<administrative transfer to H10W 72/075 and H10W 72/01571 simultaneously>
D	H01L2224/85914	5	Thermal cleaning, e.g. using laser ablation or by electrostatic corona discharge	<administrative transfer to H10W 72/075 and H10W 72/01571 simultaneously>
D	H01L2224/85916	6	using a laser	<administrative transfer to H10W 72/075 and H10W 72/01571 simultaneously>
D	H01L2224/85917	5	Electron beam cleaning	<administrative transfer to H10W 72/075 and H10W 72/01571 simultaneously>
D	H01L2224/85919	5	Combinations of two or more cleaning methods provided for in at least two different groups from H01L2224/8591 - H01L2224/85914	<administrative transfer to H10W 72/075 and H10W 72/01571 simultaneously>
D	H01L2224/8592	4	Applying permanent coating, e.g. protective coating	<administrative transfer to H10W 72/075 and H10W 72/01515 simultaneously>
D	H01L2224/8593	4	Reshaping, e.g. for severing the wire, modifying the wedge or ball or the loop shape	<administrative transfer to H10W 72/075 and H10W 72/01551 simultaneously>

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D	H01L2224/85931	5	by chemical means, e.g. etching	<administrative transfer to H10W 72/075 and H10W 72/01553 simultaneously>
D	H01L2224/85935	5	by heating means, e.g. reflowing	<administrative transfer to H10W 72/075 and H10W 72/01551 simultaneously>
D	H01L2224/85937	6	using a polychromatic heating lamp	<administrative transfer to H10W 72/075 and H10W 72/01551 simultaneously>
D	H01L2224/85939	6	using a laser	<administrative transfer to H10W 72/075 and H10W 72/01551 simultaneously>
D	H01L2224/85941	6	Induction heating, i.e. eddy currents	<administrative transfer to H10W 72/075 and H10W 72/01551 simultaneously>
D	H01L2224/85943	6	using a flame torch, e.g. hydrogen torch	<administrative transfer to H10W 72/075 and H10W 72/01551 simultaneously>
D	H01L2224/85945	6	using a corona discharge, e.g. electronic flame off [EFO]	<administrative transfer to H10W 72/075 and H10W 72/01551 simultaneously>
D	H01L2224/85947	5	by mechanical means, e.g. "pull-and-cut", pressing, stamping	<administrative transfer to H10W 72/075 and H10W 72/01551 simultaneously>
D	H01L2224/85948	4	Thermal treatments, e.g. annealing, controlled cooling	<administrative transfer to H10W 72/075 and H10W 72/01551 simultaneously>
D	H01L2224/85951	4	Forming additional members, e.g. for reinforcing	<administrative transfer to H10W 72/075 and H10W 72/01551 simultaneously>
D	H01L2224/85986	3	Specific sequence of steps, e.g. repetition of manufacturing steps, time sequence	<administrative transfer to H10W 72/075>
D	H01L2224/86	2	using tape automated bonding [TAB]	<administrative transfer to H10W 72/077>
D	H01L2224/86001	3	involving a temporary auxiliary member not forming part of the bonding apparatus	<administrative transfer to H10W 72/077>
D	H01L2224/86002	4	being a removable or sacrificial coating	<administrative transfer to H10W 72/077>
D	H01L2224/86005	4	being a temporary or sacrificial substrate	<administrative transfer to H10W 72/077>

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D	H01L2224/86007	3	involving a permanent auxiliary member being left in the finished device, e.g. aids for holding or protecting the TAB connector during or after the bonding process	<administrative transfer to H10W 72/077>
D	H01L2224/86009	3	Pre-treatment of the connector or the bonding area	<administrative transfer to H10W 72/077>
D	H01L2224/8601	4	Cleaning, e.g. oxide removal step, desmearing	<administrative transfer to H10W 72/077>
D	H01L2224/8603	4	Reshaping	<administrative transfer to H10W 72/077>
D	H01L2224/86031	5	by chemical means, e.g. etching, anodisation	<administrative transfer to H10W 72/077>
D	H01L2224/86035	5	by heating	<administrative transfer to H10W 72/077>
D	H01L2224/86039	6	using a laser	<administrative transfer to H10W 72/077>
D	H01L2224/86045	6	using a corona discharge, e.g. electronic flame off [EFO]	<administrative transfer to H10W 72/077>
D	H01L2224/86047	5	by mechanical means, e.g. severing, pressing, stamping	<administrative transfer to H10W 72/077>
D	H01L2224/86048	4	Thermal treatment, e.g. annealing, controlled pre-heating or pre-cooling	<administrative transfer to H10W 72/077>
D	H01L2224/86051	4	Forming additional members	<administrative transfer to H10W 72/077>
D	H01L2224/86053	3	Bonding environment	<administrative transfer to H10W 72/077>
D	H01L2224/86054	4	Composition of the atmosphere	<administrative transfer to H10W 72/077>
D	H01L2224/86085	4	being a liquid, e.g. fluidic self-assembly	<administrative transfer to H10W 72/077>
D	H01L2224/8609	4	Vacuum	<administrative transfer to H10W 72/077>
D	H01L2224/86091	4	Under pressure	<administrative transfer to H10W 72/077>
D	H01L2224/86095	4	Temperature settings	<administrative transfer to H10W 72/077>
D	H01L2224/86096	5	Transient conditions	<administrative transfer to H10W 72/077>
D	H01L2224/86097	6	Heating	<administrative transfer to H10W 72/077>
D	H01L2224/86098	6	Cooling	<administrative transfer to H10W 72/077>
D	H01L2224/86099	5	Ambient temperature	<administrative transfer to H10W 72/077>
D	H01L2224/861	3	the connector being supplied to the parts to be connected in the bonding apparatus	<administrative transfer to H10W 72/077>
D	H01L2224/8611	3	involving protection against electrical discharge, e.g. removing electrostatic charge	<administrative transfer to H10W 72/077>

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D	H01L2224/8612	3	Aligning	<administrative transfer to H10W 72/077>
D	H01L2224/86121	4	Active alignment, i.e. by apparatus steering, e.g. optical alignment using marks or sensors	<administrative transfer to H10W 72/077>
D	H01L2224/86122	5	by detecting inherent features of, or outside, the semiconductor or solid-state body	<administrative transfer to H10W 72/077>
D	H01L2224/8613	5	using marks formed on the semiconductor or solid-state body	<administrative transfer to H10W 72/077>
D	H01L2224/86132	5	using marks formed outside the semiconductor or solid-state body, i.e. "off-chip"	<administrative transfer to H10W 72/077>
D	H01L2224/86136	4	involving guiding structures, e.g. spacers or supporting members	<administrative transfer to H10W 72/077>
D	H01L2224/86138	5	the guiding structures being at least partially left in the finished device	<administrative transfer to H10W 72/077>
D	H01L2224/86143	4	Passive alignment, i.e. self alignment, e.g. using surface energy, chemical reactions, thermal equilibrium	<administrative transfer to H10W 72/077>
D	H01L2224/86148	4	involving movement of a part of the bonding apparatus	<administrative transfer to H10W 72/077>
D	H01L2224/86149	5	being the lower part of the bonding apparatus, i.e. holding means for the bodies to be connected, e.g. XY table	<administrative transfer to H10W 72/077>
D	H01L2224/8615	6	Rotational movements	<administrative transfer to H10W 72/077>
D	H01L2224/8616	6	Translational movements	<administrative transfer to H10W 72/077>
D	H01L2224/86169	5	being the upper part of the bonding apparatus, e.g. nozzle	<administrative transfer to H10W 72/077>
D	H01L2224/8617	6	Rotational movement	<administrative transfer to H10W 72/077>
D	H01L2224/8618	6	Translational movements	<administrative transfer to H10W 72/077>
D	H01L2224/86181	7	connecting first on the semiconductor or solid-state body, i.e. on-chip,	<administrative transfer to H10W 72/077>
D	H01L2224/86186	7	connecting first outside the semiconductor or solid-state body, i.e. off-chip	<administrative transfer to H10W 72/077>
D	H01L2224/86191	7	connecting first both on and outside the semiconductor or solid-state body	<administrative transfer to H10W 72/077>
D	H01L2224/862	3	Applying energy for connecting	<administrative transfer to H10W 72/077>
D	H01L2224/86201	4	Compression bonding	<administrative transfer to H10W 72/077>
D	H01L2224/86203	5	Thermo-compression bonding	<administrative transfer to H10W 72/077>
D	H01L2224/86205	5	Ultrasonic bonding	<administrative transfer to H10W 72/077>

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D	H01L2224/86207	6	Thermosonic bonding	<administrative transfer to H10W 72/077>
D	H01L2224/8621	4	with energy being in the form of electromagnetic radiation	<administrative transfer to H10W 72/077>
D	H01L2224/86212	5	Induction heating, i.e. eddy currents	<administrative transfer to H10W 72/077>
D	H01L2224/86214	5	using a laser	<administrative transfer to H10W 72/077>
D	H01L2224/8623	5	Polychromatic or infrared lamp heating	<administrative transfer to H10W 72/077>
D	H01L2224/86232	5	using an autocatalytic reaction, e.g. exothermic brazing	<administrative transfer to H10W 72/077>
D	H01L2224/86234	5	using means for applying energy being within the device, e.g. integrated heater	<administrative transfer to H10W 72/077>
D	H01L2224/86236	5	using electro-static corona discharge	<administrative transfer to H10W 72/077>
D	H01L2224/86237	5	using electron beam	<administrative transfer to H10W 72/077>
D	H01L2224/86238	5	using electric resistance welding, i.e. ohmic heating	<administrative transfer to H10W 72/077>
D	H01L2224/8634	3	Bonding interfaces of the connector	<administrative transfer to H10W 72/077>
D	H01L2224/86345	4	Shape, e.g. interlocking features	<administrative transfer to H10W 72/077>
D	H01L2224/86355	4	having an external coating, e.g. protective bond-through coating	<administrative transfer to H10W 72/077>
D	H01L2224/86359	4	Material	<administrative transfer to H10W 72/077>
D	H01L2224/8636	3	Bonding interfaces of the semiconductor or solid state body	<administrative transfer to H10W 72/077>
D	H01L2224/86365	4	Shape, e.g. interlocking features	<administrative transfer to H10W 72/077>
D	H01L2224/86375	4	having an external coating, e.g. protective bond-through coating	<administrative transfer to H10W 72/077>
D	H01L2224/86379	4	Material	<administrative transfer to H10W 72/077>
D	H01L2224/8638	3	Bonding interfaces outside the semiconductor or solid-state body	<administrative transfer to H10W 72/077>
D	H01L2224/86385	4	Shape, e.g. interlocking features	<administrative transfer to H10W 72/077>
D	H01L2224/86395	4	having an external coating, e.g. protective bond-through coating	<administrative transfer to H10W 72/077>
D	H01L2224/86399	4	Material	<administrative transfer to H10W 72/077>
D	H01L2224/868	3	Bonding techniques	<administrative transfer to H10W 72/077>
D	H01L2224/86801	4	Soldering or alloying	<administrative transfer to H10W 72/077>

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D	H01L2224/86805	5	involving forming a eutectic alloy at the bonding interface	<administrative transfer to H10W 72/077>
D	H01L2224/8681	5	involving forming an intermetallic compound at the bonding interface	<administrative transfer to H10W 72/077>
D	H01L2224/86815	5	Reflow soldering	<administrative transfer to H10W 72/077>
D	H01L2224/8682	5	Diffusion bonding	<administrative transfer to H10W 72/077>
D	H01L2224/86825	6	Solid-liquid interdiffusion	<administrative transfer to H10W 72/077>
D	H01L2224/8683	6	Solid-solid interdiffusion	<administrative transfer to H10W 72/077>
D	H01L2224/8684	4	Sintering	<administrative transfer to H10W 72/077>
D	H01L2224/8685	4	using a polymer adhesive, e.g. an adhesive based on silicone, epoxy, polyimide, polyester	<administrative transfer to H10W 72/077>
D	H01L2224/86855	5	Hardening the adhesive by curing, i.e. thermosetting	<administrative transfer to H10W 72/077>
D	H01L2224/86856	6	Pre-cured adhesive, i.e. B-stage adhesive	<administrative transfer to H10W 72/077>
D	H01L2224/86859	6	Localised curing of parts of the connector	<administrative transfer to H10W 72/077>
D	H01L2224/86862	6	Heat curing	<administrative transfer to H10W 72/077>
D	H01L2224/86865	6	Microwave curing	<administrative transfer to H10W 72/077>
D	H01L2224/86868	6	Infrared [IR] curing	<administrative transfer to H10W 72/077>
D	H01L2224/86871	6	Visible light curing	<administrative transfer to H10W 72/077>
D	H01L2224/86874	6	Ultraviolet [UV] curing	<administrative transfer to H10W 72/077>
D	H01L2224/86877	6	Moisture curing, i.e. curing by exposing to humidity, e.g. for silicones and polyurethanes	<administrative transfer to H10W 72/077>
D	H01L2224/8688	5	Hardening the adhesive by cooling, e.g. for thermoplastics or hot-melt adhesives	<administrative transfer to H10W 72/077>
D	H01L2224/86885	5	Combinations of two or more hardening methods provided for in at least two different groups selected from H01L2224/86855 - H01L2224/8688, e.g. hybrid thermoplastic-thermosetting adhesives	<administrative transfer to H10W 72/077>
D	H01L2224/8689	4	using an inorganic non metallic glass type adhesive, e.g. solder glass	<administrative transfer to H10W 72/077>
D	H01L2224/86893	4	Anodic bonding, i.e. bonding by applying a voltage across the interface in order to induce ions migration leading to an irreversible chemical bond	<administrative transfer to H10W 72/077>

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D	H01L2224/86895	4	Direct bonding, i.e. joining surfaces by means of intermolecular attracting interactions at their interfaces, e.g. covalent bonds, van der Waals forces	<administrative transfer to H10W 72/077>
D	H01L2224/86896	5	between electrically conductive surfaces, e.g. copper-copper direct bonding, surface activated bonding	<administrative transfer to H10W 72/077>
D	H01L2224/86897	5	between electrically insulating surfaces, e.g. oxide or nitride layers	<administrative transfer to H10W 72/077>
D	H01L2224/86899	4	Combinations of bonding methods provided for in at least two different groups from H01L2224/868 - H01L2224/86897	<administrative transfer to H10W 72/077>
D	H01L2224/869	3	involving monitoring, e.g. feedback loop	<administrative transfer to H10W 72/077>
D	H01L2224/86909	3	Post-treatment of the connector or the bonding area	<administrative transfer to H10W 72/077>
D	H01L2224/8691	4	Cleaning, e.g. oxide removal step, desmearing	<administrative transfer to H10W 72/077>
D	H01L2224/8693	4	Reshaping	<administrative transfer to H10W 72/077>
D	H01L2224/86931	5	by chemical means, e.g. etching, anodisation	<administrative transfer to H10W 72/077>
D	H01L2224/86935	5	by heating means	<administrative transfer to H10W 72/077>
D	H01L2224/86939	6	using a laser	<administrative transfer to H10W 72/077>
D	H01L2224/86945	6	using a corona discharge, e.g. electronic flame off [EFO]	<administrative transfer to H10W 72/077>
D	H01L2224/86947	5	by mechanical means, e.g. severing, pressing, stamping	<administrative transfer to H10W 72/077>
D	H01L2224/86948	4	Thermal treatments, e.g. annealing, controlled pre-heating or pre-cooling	<administrative transfer to H10W 72/077>
D	H01L2224/86951	4	Forming additional members	<administrative transfer to H10W 72/077>
D	H01L2224/86986	3	Specific sequence of steps, e.g. repetition of manufacturing steps, time sequence	<administrative transfer to H10W 72/077>
D	H01L2224/89	2	using at least one connector not provided for in any of the groups H01L2224/81 - H01L2224/86	<administrative transfer to H10W 72/00>
D	H01L2224/90	1	Methods for connecting semiconductor or solid state bodies using means for bonding not being attached to, or not being formed on, the body surface to be connected, e.g. pressure contacts using springs or clips	<administrative transfer to H10W 72/00>
D	H01L2224/91	1	Methods for connecting semiconductor or solid state bodies including different methods provided for in two or more of groups H01L2224/80 - H01L2224/90	<administrative transfer to H10W 99/00>

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D	H01L2224/92	2	Specific sequence of method steps	<administrative transfer to H10W 99/00>
D	H01L2224/9201	3	Forming connectors during the connecting process, e.g. in-situ formation of bumps	<administrative transfer to H10W 99/00>
D	H01L2224/9202	3	Forming additional connectors after the connecting process	<administrative transfer to H10W 99/00>
D	H01L2224/9205	3	Intermediate bonding steps, i.e. partial connection of the semiconductor or solid-state body during the connecting process	<administrative transfer to H10W 99/00>
D	H01L2224/921	3	Connecting a surface with connectors of different types	<administrative transfer to H10W 99/00>
D	H01L2224/9211	4	Parallel connecting processes	<administrative transfer to H10W 99/00>
D	H01L2224/9212	4	Sequential connecting processes	<administrative transfer to H10W 99/00>
D	H01L2224/92122	5	the first connecting process involving a bump connector	<administrative transfer to H10W 72/072>
D	H01L2224/92124	6	the second connecting process involving a build-up interconnect	<administrative transfer to H10W 72/072 and H10W 70/099 simultaneously>
D	H01L2224/92125	6	the second connecting process involving a layer connector	<administrative transfer to H10W 72/072 and H10W 72/073 simultaneously>
D	H01L2224/92127	6	the second connecting process involving a wire connector	<administrative transfer to H10W 72/072 and H10W 72/075 simultaneously>
D	H01L2224/92132	5	the first connecting process involving a build-up interconnect	<administrative transfer to H10W 70/099>
D	H01L2224/92133	6	the second connecting process involving a bump connector	<administrative transfer to H10W 70/099 and H10W 72/072 simultaneously>
D	H01L2224/92135	6	the second connecting process involving a layer connector	<administrative transfer to H10W 70/099 and H10W 72/073 simultaneously>
D	H01L2224/92136	6	the second connecting process involving a strap connector	<administrative transfer to H10W 70/099 and H10W 72/076 simultaneously>
D	H01L2224/92137	6	the second connecting process involving a wire connector	<administrative transfer to H10W 70/099 and H10W 72/075 simultaneously>
D	H01L2224/92138	6	the second connecting process involving a TAB connector	<administrative transfer to H10W 70/099 and

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				H10W 72/077 simultaneously>
D	H01L2224/92142	5	the first connecting process involving a layer connector	<administrative transfer to H10W 72/073>
D	H01L2224/92143	6	the second connecting process involving a bump connector	<administrative transfer to H10W 72/073 and H10W 72/072 simultaneously>
D	H01L2224/92144	6	the second connecting process involving a build-up interconnect	<administrative transfer to H10W 72/073 and H10W 70/093 simultaneously>
D	H01L2224/92147	6	the second connecting process involving a wire connector	<administrative transfer to H10W 72/073 and H10W 72/075 simultaneously>
D	H01L2224/92148	6	the second connecting process involving a TAB connector	<administrative transfer to H10W 72/073 and H10W 72/077 simultaneously>
D	H01L2224/92152	5	the first connecting process involving a strap connector	<administrative transfer to H10W 72/076>
D	H01L2224/92153	6	the second connecting process involving a bump connector	<administrative transfer to H10W 72/076 and H10W 72/072 simultaneously>
D	H01L2224/92155	6	the second connecting process involving a layer connector	<administrative transfer to H10W 72/073 and H10W 72/076 simultaneously>
D	H01L2224/92157	6	the second connecting process involving a wire connector	<administrative transfer to H10W 72/076 and H10W 72/075 simultaneously>
D	H01L2224/92158	6	the second connecting process involving a TAB connector	<administrative transfer to H10W 72/076 and H10W 72/077 simultaneously>
D	H01L2224/92162	5	the first connecting process involving a wire connector	<administrative transfer to H10W 72/075>
D	H01L2224/92163	6	the second connecting process involving a bump connector	<administrative transfer to H10W 72/075 and H10W 72/072 simultaneously>
D	H01L2224/92164	6	the second connecting process involving a build-up interconnect	<administrative transfer to H10W 72/075 and H10W 70/093 simultaneously>
D	H01L2224/92165	6	the second connecting process involving a layer connector	<administrative transfer to H10W 72/075 and

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				H10W 72/073 simultaneously>
D	H01L2224/92166	6	the second connecting process involving a strap connector	<administrative transfer to H10W 72/075 and H10W 72/076 simultaneously>
D	H01L2224/92168	6	the second connecting process involving a TAB connector	<administrative transfer to H10W 72/075 and H10W 72/077 simultaneously>
D	H01L2224/92172	5	the first connecting process involving a TAB connector	<administrative transfer to H10W 72/077>
D	H01L2224/92173	6	the second connecting process involving a bump connector	<administrative transfer to H10W 72/077 and H10W 72/072 simultaneously>
D	H01L2224/92174	6	the second connecting process involving a build-up interconnect	<administrative transfer to H10W 72/077 and H10W 70/093 simultaneously>
D	H01L2224/92175	6	the second connecting process involving a layer connector	<administrative transfer to H10W 72/077 and H10W 72/073 simultaneously>
D	H01L2224/92176	6	the second connecting process involving a strap connector	<administrative transfer to H10W 72/077 and H10W 72/076 simultaneously>
D	H01L2224/92177	6	the second connecting process involving a wire connector	<administrative transfer to H10W 72/077 and H10W 72/075 simultaneously>
D	H01L2224/922	3	Connecting different surfaces of the semiconductor or solid-state body with connectors of different types	<no transfer>
D	H01L2224/9221	4	Parallel connecting processes	<no transfer>
D	H01L2224/9222	4	Sequential connecting processes	<no transfer>
D	H01L2224/92222	5	the first connecting process involving a bump connector	<administrative transfer to H10W 72/072>
D	H01L2224/92224	6	the second connecting process involving a build-up interconnect	<administrative transfer to H10W 72/072 and H10W 70/099 simultaneously>
D	H01L2224/92225	6	the second connecting process involving a layer connector	<administrative transfer to H10W 72/072 and H10W 72/073 simultaneously>
D	H01L2224/92226	6	the second connecting process involving a strap connector	<administrative transfer to H10W 72/072 and

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				H10W 72/076 simultaneously>
D	H01L2224/92227	6	the second connecting process involving a wire connector	<administrative transfer to H10W 72/072 and H10W 72/075 simultaneously>
D	H01L2224/92228	6	the second connecting process involving a TAB connector	<administrative transfer to H10W 72/072 and H10W 72/077 simultaneously>
D	H01L2224/92242	5	the first connecting process involving a layer connector	<administrative transfer to H10W 72/073>
D	H01L2224/92244	6	the second connecting process involving a build-up interconnect	<administrative transfer to H10W 72/073 and H10W 70/099 simultaneously>
D	H01L2224/92246	6	the second connecting process involving a strap connector	<administrative transfer to H10W 72/073 and H10W 72/076 simultaneously>
D	H01L2224/92247	6	the second connecting process involving a wire connector	<administrative transfer to H10W 72/073 and H10W 72/075 simultaneously>
D	H01L2224/92248	6	the second connecting process involving a TAB connector	<administrative transfer to H10W 72/073 and H10W 72/077 simultaneously>
D	H01L2224/92252	5	the first connecting process involving a strap connector	<administrative transfer to H10W 72/076>
D	H01L2224/92253	6	the second connecting process involving a bump connector	<administrative transfer to H10W 72/076 and H10W 72/072 simultaneously>
D	H01L2224/92255	6	the second connecting process involving a layer connector	<administrative transfer to H10W 72/076 and H10W 72/073 simultaneously>
D	H01L2224/93	1	Batch processes	<administrative transfer to H10W 72/0198>
D	H01L2224/94	2	at wafer-level, i.e. with connecting carried out on a wafer comprising a plurality of undiced individual devices	<administrative transfer to H10W 72/0198>
D	H01L2224/95	2	at chip-level, i.e. with connecting carried out on a plurality of singulated devices, i.e. on diced chips	<administrative transfer to H10W 72/0198>
D	H01L2224/95001	3	involving a temporary auxiliary member not forming part of the bonding apparatus, e.g. removable or sacrificial coating, film or substrate	<administrative transfer to H10W 72/0198>

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D	H01L2224/95053	3	Bonding environment	<administrative transfer to H10W 72/0198>
D	H01L2224/95085	4	being a liquid, e.g. for fluidic self-assembly	<administrative transfer to H10W 72/0198>
D	H01L2224/95091	4	Under pressure	<administrative transfer to H10W 72/0198>
D	H01L2224/95092	5	Atmospheric pressure, e.g. dry self-assembly	<administrative transfer to H10W 72/0198>
D	H01L2224/95093	5	Transient conditions, e.g. assisted by a gas flow or a liquid flow	<administrative transfer to H10W 72/0198>
D	H01L2224/951	3	Supplying the plurality of semiconductor or solid-state bodies	<administrative transfer to H10W 72/0198>
D	H01L2224/95101	4	in a liquid medium	<administrative transfer to H10W 72/0198>
D	H01L2224/95102	5	being a colloidal droplet	<administrative transfer to H10W 72/0198>
D	H01L2224/9511	4	using a rack or rail	<administrative transfer to H10W 72/0198>
D	H01L2224/95115	4	using a roll-to-roll transfer technique	<administrative transfer to H10W 72/0198>
D	H01L2224/9512	3	Aligning the plurality of semiconductor or solid-state bodies	<administrative transfer to H10W 72/0198>
D	H01L2224/95121	4	Active alignment, i.e. by apparatus steering	<administrative transfer to H10W 72/0198>
D	H01L2224/95122	5	by applying vibration	<administrative transfer to H10W 72/0198>
D	H01L2224/95123	5	by applying a pressurised fluid flow, e.g. liquid or gas flow	<administrative transfer to H10W 72/0198>
D	H01L2224/95133	5	by applying an electromagnetic field	<administrative transfer to H10W 72/0198>
D	H01L2224/95134	6	Electrowetting, i.e. by changing the surface energy of a droplet	<administrative transfer to H10W 72/0198>
D	H01L2224/95136	4	involving guiding structures, e.g. shape matching, spacers or supporting members	<administrative transfer to H10W 72/0198>
D	H01L2224/95143	4	Passive alignment, i.e. self alignment, e.g. using surface energy, chemical reactions, thermal equilibrium	<administrative transfer to H10W 72/0198>
D	H01L2224/95144	5	Magnetic alignment, i.e. using permanent magnetic parts in the semiconductor or solid-state body	<administrative transfer to H10W 72/0198>
D	H01L2224/95145	5	Electrostatic alignment, i.e. polarity alignment with Coulomb charges	<administrative transfer to H10W 72/0198>
D	H01L2224/95146	5	by surface tension	<administrative transfer to H10W 72/0198>
D	H01L2224/95147	5	by molecular lock-key, e.g. by DNA	<administrative transfer to H10W 72/0198>
D	H01L2224/95148	4	involving movement of a part of the bonding apparatus	<administrative transfer to H10W 72/0198>

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D	H01L2224/96	3	the devices being encapsulated in a common layer, e.g. neo-wafer or pseudo-wafer, said common layer being separable into individual assemblies after connecting	<administrative transfer to H10W 72/0198>
D	H01L2224/97	3	the devices being connected to a common substrate, e.g. interposer, said common substrate being separable into individual assemblies after connecting	<administrative transfer to H10W 72/0198>
D	H01L2224/98	1	Methods for disconnecting semiconductor or solid-state bodies	<administrative transfer to H10W 72/071>
D	H01L2225/00	0	Details relating to assemblies covered by the group H01L25/00 but not provided for in its subgroups	<administrative transfer to H10W 90/00>
D	H01L2225/03	1	All the devices being of a type provided for in the same main group of the same subclass of class H10, e.g. assemblies of rectifier diodes	<administrative transfer to H10W 90/00>
D	H01L2225/04	2	the devices not having separate containers	<administrative transfer to H10W 90/00>
D	H01L2225/065	3	All the devices being of a type provided for in the same main group of the same subclass of class H10	<administrative transfer to H10W 90/00>
D	H01L2225/06503	4	Stacked arrangements of devices	<administrative transfer to H10W 90/20>
D	H01L2225/06506	5	Wire or wire-like electrical connections between devices	<administrative transfer to H10W 90/752>
D	H01L2225/0651	5	Wire or wire-like electrical connections from device to substrate	<administrative transfer to H10W 90/754>
D	H01L2225/06513	5	Bump or bump-like direct electrical connections between devices, e.g. flip-chip connection, solder bumps	<administrative transfer to H10W 90/722>
D	H01L2225/06517	5	Bump or bump-like direct electrical connections from device to substrate	<administrative transfer to H10W 90/724>
D	H01L2225/0652	5	Bump or bump-like direct electrical connections from substrate to substrate	<administrative transfer to H10W 90/721>
D	H01L2225/06524	5	Electrical connections formed on device or on substrate, e.g. a deposited or grown layer	<administrative transfer to H10W 90/20>
D	H01L2225/06527	5	Special adaptation of electrical connections, e.g. rewiring, engineering changes, pressure contacts, layout	<administrative transfer to H10W 72/01>
D	H01L2225/06531	6	Non-galvanic coupling, e.g. capacitive coupling	<administrative transfer to H10W 90/293>
D	H01L2225/06534	7	Optical coupling	<administrative transfer to H10W 90/295>
D	H01L2225/06537	6	Electromagnetic shielding	<administrative transfer to H10W 42/271>
D	H01L2225/06541	5	Conductive via connections through the device, e.g. vertical interconnects, through silicon via [TSV]	<administrative transfer to H10W 90/297>

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D	H01L2225/06544	6	Design considerations for via connections, e.g. geometry or layout	<administrative transfer to H10W 90/297>
D	H01L2225/06548	5	Conductive via connections through the substrate, container, or encapsulation	<administrative transfer to H10W 72/823>
D	H01L2225/06551	5	Conductive connections on the side of the device	<administrative transfer to H10W 72/834>
D	H01L2225/06555	5	Geometry of the stack, e.g. form of the devices, geometry to facilitate stacking	<administrative transfer to H10W 90/20>
D	H01L2225/06558	6	the devices having passive surfaces facing each other, i.e. in a back-to-back arrangement	<administrative transfer to H10W 90/271>
D	H01L2225/06562	6	at least one device in the stack being rotated or offset	<administrative transfer to H10W 90/24>
D	H01L2225/06565	6	the devices having the same size and there being no auxiliary carrier between the devices	<administrative transfer to H10W 90/26>
D	H01L2225/06568	6	the devices decreasing in size, e.g. pyramidal stack	<administrative transfer to H10W 90/28>
D	H01L2225/06572	5	Auxiliary carrier between devices, the carrier having an electrical connection structure	<administrative transfer to H10W 90/22>
D	H01L2225/06575	5	Auxiliary carrier between devices, the carrier having no electrical connection structure	<administrative transfer to H10W 90/231>
D	H01L2225/06579	5	TAB carriers; beam leads	<administrative transfer to H10W 72/60>
D	H01L2225/06582	5	Housing for the assembly, e.g. chip scale package [CSP]	<administrative transfer to H10W 90/291>
D	H01L2225/06586	6	Housing with external bump or bump-like connectors	<administrative transfer to H10W 90/291>
D	H01L2225/06589	5	Thermal management, e.g. cooling	<administrative transfer to H10W 90/288>
D	H01L2225/06593	5	Mounting aids permanently on device; arrangements for alignment	<administrative transfer to H10W 46/00>
D	H01L2225/06596	5	Structural arrangements for testing	<administrative transfer to H10W 90/284>
D	H01L2225/10	2	the devices having separate containers	<administrative transfer to H10W 90/20>
D	H01L2225/1005	3	the devices being integrated devices of class H10	<administrative transfer to H10W 90/20>
D	H01L2225/1011	4	the containers being in a stacked arrangement	<administrative transfer to H10W 90/20>
D	H01L2225/1017	5	the lowermost container comprising a device support	<administrative transfer to H10W 90/20>
D	H01L2225/1023	6	the support being an insulating substrate	<administrative transfer to H10W 70/60>
D	H01L2225/1029	6	the support being a lead frame	<administrative transfer to H10W 70/40>
D	H01L2225/1035	6	the device being entirely enclosed by the support, e.g. high-density interconnect [HDI]	<administrative transfer to H10W 70/60>

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D	H01L2225/1041	5	Special adaptations for top connections of the lowermost container, e.g. redistribution layer, integral interposer	<administrative transfer to H10W 70/60>
D	H01L2225/1047	5	Details of electrical connections between containers	<administrative transfer to H10W 90/701>
D	H01L2225/1052	6	Wire or wire-like electrical connections	<administrative transfer to H10W 90/752>
D	H01L2225/1058	6	Bump or bump-like electrical connections, e.g. balls, pillars, posts	<administrative transfer to H10W 90/722>
D	H01L2225/1064	6	Electrical connections provided on a side surface of one or more of the containers	<administrative transfer to H10W 72/801>
D	H01L2225/107	6	Indirect electrical connections, e.g. via an interposer, a flexible substrate, using TAB	<administrative transfer to H10W 70/60>
D	H01L2225/1076	5	Shape of the containers	<administrative transfer to H10W 90/291>
D	H01L2225/1082	6	for improving alignment between containers, e.g. interlocking features	<administrative transfer to H10W 90/291>
D	H01L2225/1088	6	Arrangements to limit the height of the assembly	<administrative transfer to H10W 90/291>
D	H01L2225/1094	5	Thermal management, e.g. cooling	<administrative transfer to H10W 90/288>
D	H01L2924/00	0	Indexing scheme for arrangements or methods for connecting or disconnecting semiconductor or solid-state bodies as covered by H01L24/00	<no transfer>
D	H01L2924/0001	1	Technical content checked by a classifier	<no transfer>
D	H01L2924/00011	2	Not relevant to the scope of the group, the symbol of which is combined with the symbol of this group	<no transfer>
D	H01L2924/00012	2	Relevant to the scope of the group, the symbol of which is combined with the symbol of this group	<no transfer>
D	H01L2924/00013	2	Fully indexed content	<no transfer>
D	H01L2924/00014	2	the subject-matter covered by the group, the symbol of which is combined with the symbol of this group, being disclosed without further technical details	<no transfer>
D	H01L2924/00015	2	the subject-matter covered by the group, the symbol of which is combined with the symbol of this group, being disclosed as prior art	<no transfer>
D	H01L2924/0002	2	Not covered by any one of groups H01L24/00, H01L24/00 and H01L2224/00	<no transfer>
D	H01L2924/01	1	Chemical elements	<no transfer>
D	H01L2924/01001	2	Hydrogen [H]	<no transfer>
D	H01L2924/01002	2	Helium [He]	<no transfer>
D	H01L2924/01003	2	Lithium [Li]	<no transfer>

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D	H01L2924/01004	2	Beryllium [Be]	<no transfer>
D	H01L2924/01005	2	Boron [B]	<no transfer>
D	H01L2924/01006	2	Carbon [C]	<no transfer>
D	H01L2924/01007	2	Nitrogen [N]	<no transfer>
D	H01L2924/01008	2	Oxygen [O]	<no transfer>
D	H01L2924/01009	2	Fluorine [F]	<no transfer>
D	H01L2924/0101	2	Neon [Ne]	<no transfer>
D	H01L2924/01011	2	Sodium [Na]	<no transfer>
D	H01L2924/01012	2	Magnesium [Mg]	<no transfer>
D	H01L2924/01013	2	Aluminum [Al]	<no transfer>
D	H01L2924/01014	2	Silicon [Si]	<no transfer>
D	H01L2924/01015	2	Phosphorus [P]	<no transfer>
D	H01L2924/01016	2	Sulfur [S]	<no transfer>
D	H01L2924/01017	2	Chlorine [Cl]	<no transfer>
D	H01L2924/01018	2	Argon [Ar]	<no transfer>
D	H01L2924/01019	2	Potassium [K]	<no transfer>
D	H01L2924/0102	2	Calcium [Ca]	<no transfer>
D	H01L2924/01021	2	Scandium [Sc]	<no transfer>
D	H01L2924/01022	2	Titanium [Ti]	<no transfer>
D	H01L2924/01023	2	Vanadium [V]	<no transfer>
D	H01L2924/01024	2	Chromium [Cr]	<no transfer>
D	H01L2924/01025	2	Manganese [Mn]	<no transfer>
D	H01L2924/01026	2	Iron [Fe]	<no transfer>
D	H01L2924/01027	2	Cobalt [Co]	<no transfer>
D	H01L2924/01028	2	Nickel [Ni]	<no transfer>
D	H01L2924/01029	2	Copper [Cu]	<no transfer>
D	H01L2924/0103	2	Zinc [Zn]	<no transfer>
D	H01L2924/01031	2	Gallium [Ga]	<no transfer>
D	H01L2924/01032	2	Germanium [Ge]	<no transfer>
D	H01L2924/01033	2	Arsenic [As]	<no transfer>
D	H01L2924/01034	2	Selenium [Se]	<no transfer>
D	H01L2924/01035	2	Bromine [Br]	<no transfer>
D	H01L2924/01036	2	Krypton [Kr]	<no transfer>
D	H01L2924/01037	2	Rubidium [Rb]	<no transfer>
D	H01L2924/01038	2	Strontium [Sr]	<no transfer>
D	H01L2924/01039	2	Yttrium [Y]	<no transfer>
D	H01L2924/0104	2	Zirconium [Zr]	<no transfer>
D	H01L2924/01041	2	Niobium [Nb]	<no transfer>
D	H01L2924/01042	2	Molybdenum [Mo]	<no transfer>
D	H01L2924/01043	2	Technetium [Tc]	<no transfer>

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D	H01L2924/01044	2	Ruthenium [Ru]	<no transfer>
D	H01L2924/01045	2	Rhodium [Rh]	<no transfer>
D	H01L2924/01046	2	Palladium [Pd]	<no transfer>
D	H01L2924/01047	2	Silver [Ag]	<no transfer>
D	H01L2924/01048	2	Cadmium [Cd]	<no transfer>
D	H01L2924/01049	2	Indium [In]	<no transfer>
D	H01L2924/0105	2	Tin [Sn]	<no transfer>
D	H01L2924/01051	2	Antimony [Sb]	<no transfer>
D	H01L2924/01052	2	Tellurium [Te]	<no transfer>
D	H01L2924/01053	2	Iodine [I]	<no transfer>
D	H01L2924/01054	2	Xenon [Xe]	<no transfer>
D	H01L2924/01055	2	Cesium [Cs]	<no transfer>
D	H01L2924/01056	2	Barium [Ba]	<no transfer>
D	H01L2924/01057	2	Lanthanum [La]	<no transfer>
D	H01L2924/01058	2	Cerium [Ce]	<no transfer>
D	H01L2924/01059	2	Praseodymium [Pr]	<no transfer>
D	H01L2924/0106	2	Neodymium [Nd]	<no transfer>
D	H01L2924/01061	2	Promethium [Pm]	<no transfer>
D	H01L2924/01062	2	Samarium [Sm]	<no transfer>
D	H01L2924/01063	2	Europium [Eu]	<no transfer>
D	H01L2924/01064	2	Gadolinium [Gd]	<no transfer>
D	H01L2924/01065	2	Terbium [Tb]	<no transfer>
D	H01L2924/01066	2	Dysprosium [Dy]	<no transfer>
D	H01L2924/01067	2	Holmium [Ho]	<no transfer>
D	H01L2924/01068	2	Erbium [Er]	<no transfer>
D	H01L2924/01069	2	Thulium [Tm]	<no transfer>
D	H01L2924/0107	2	Ytterbium [Yb]	<no transfer>
D	H01L2924/01071	2	Lutetium [Lu]	<no transfer>
D	H01L2924/01072	2	Hafnium [Hf]	<no transfer>
D	H01L2924/01073	2	Tantalum [Ta]	<no transfer>
D	H01L2924/01074	2	Tungsten [W]	<no transfer>
D	H01L2924/01075	2	Rhenium [Re]	<no transfer>
D	H01L2924/01076	2	Osmium [Os]	<no transfer>
D	H01L2924/01077	2	Iridium [Ir]	<no transfer>
D	H01L2924/01078	2	Platinum [Pt]	<no transfer>
D	H01L2924/01079	2	Gold [Au]	<no transfer>
D	H01L2924/0108	2	Mercury [Hg]	<no transfer>
D	H01L2924/01081	2	Thallium [Tl]	<no transfer>
D	H01L2924/01082	2	Lead [Pb]	<no transfer>
D	H01L2924/01083	2	Bismuth [Bi]	<no transfer>

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D	H01L2924/01084	2	Polonium [Po]	<no transfer>
D	H01L2924/01085	2	Astatine [At]	<no transfer>
D	H01L2924/01086	2	Radon [Rn]	<no transfer>
D	H01L2924/01087	2	Francium [Fr]	<no transfer>
D	H01L2924/01088	2	Radium [Ra]	<no transfer>
D	H01L2924/01089	2	Actinium [Ac]	<no transfer>
D	H01L2924/0109	2	Thorium [Th]	<no transfer>
D	H01L2924/01091	2	Protactinium [Pa]	<no transfer>
D	H01L2924/01092	2	Uranium [U]	<no transfer>
D	H01L2924/01093	2	Neptunium [Np]	<no transfer>
D	H01L2924/01094	2	Plutonium [Pu]	<no transfer>
D	H01L2924/011	1	Groups of the periodic table	<no transfer>
D	H01L2924/01101	2	Alkali metals	<no transfer>
D	H01L2924/01102	2	Alkali earth metals	<no transfer>
D	H01L2924/01103	2	Transition metals	<no transfer>
D	H01L2924/01104	2	Refractory metals	<no transfer>
D	H01L2924/01105	2	Rare earth metals	<no transfer>
D	H01L2924/01106	3	Lanthanides, i.e. Ce, Pr, Nd, Pm, Sm, Eu, Gd, Tb, Dy, Ho, Er, Tm, Yb, Lu	<no transfer>
D	H01L2924/01107	3	Actinides, i.e. Th, Pa, U, Np, Pu, Am, Cm, Bk, Cf, Es, Fm, Md, No, Lr	<no transfer>
D	H01L2924/01108	2	Noble metals	<no transfer>
D	H01L2924/01109	2	Metalloids or Semi-metals	<no transfer>
D	H01L2924/0111	2	Chalcogens	<no transfer>
D	H01L2924/01111	2	Halogens	<no transfer>
D	H01L2924/01112	2	Noble gases	<no transfer>
D	H01L2924/012	1	Semiconductor purity grades	<no transfer>
D	H01L2924/01201	2	1N purity grades, i.e. 90%	<no transfer>
D	H01L2924/01202	2	2N purity grades, i.e. 99%	<no transfer>
D	H01L2924/01203	2	3N purity grades, i.e. 99.9%	<no transfer>
D	H01L2924/01204	2	4N purity grades, i.e. 99.99%	<no transfer>
D	H01L2924/01205	2	5N purity grades, i.e. 99.999%	<no transfer>
D	H01L2924/01206	2	6N purity grades, i.e. 99.9999%	<no transfer>
D	H01L2924/01207	2	7N purity grades, i.e. 99.99999%	<no transfer>
D	H01L2924/01208	2	8N purity grades, i.e. 99.999999%	<no transfer>
D	H01L2924/013	1	Alloys	<no transfer>
D	H01L2924/0132	2	Binary Alloys	<no transfer>
D	H01L2924/01321	3	Isomorphous Alloys	<no transfer>
D	H01L2924/01322	3	Eutectic Alloys, i.e. obtained by a liquid transforming into two solid phases	<no transfer>

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D	H01L2924/01323	4	Hypoeutectic alloys i.e. with compositions lying to the left of the eutectic point	<no transfer>
D	H01L2924/01324	4	Hypereutectic alloys i.e. with compositions lying to the right of the eutectic point	<no transfer>
D	H01L2924/01325	3	Peritectic Alloys, i.e. obtained by a liquid and a solid transforming into a new and different solid phase	<no transfer>
D	H01L2924/01326	3	Monotectics, i.e. obtained by a liquid transforming into a solid and a new and different liquid phase	<no transfer>
D	H01L2924/01327	3	Intermediate phases, i.e. intermetallics compounds	<no transfer>
D	H01L2924/0133	2	Ternary Alloys	<no transfer>
D	H01L2924/0134	2	Quaternary Alloys	<no transfer>
D	H01L2924/0135	2	Quinary Alloys	<no transfer>
D	H01L2924/014	2	Solder alloys	<no transfer>
D	H01L2924/01402	2	Invar, i.e. single-phase alloy of around 36% nickel and 64% iron	<no transfer>
D	H01L2924/01403	2	Kovar, i.e. FeNiCo alloys	<no transfer>
D	H01L2924/01404	2	Alloy 42, i.e. FeNi42	<no transfer>
D	H01L2924/01405	2	Inovco, i.e. Fe-33Ni-4.5Co	<no transfer>
D	H01L2924/042	1	Borides composed of metals from groups of the periodic table	<no transfer>
D	H01L2924/0421	2	1st Group	<no transfer>
D	H01L2924/0422	2	2nd Group	<no transfer>
D	H01L2924/0423	2	3rd Group	<no transfer>
D	H01L2924/0424	2	4th Group	<no transfer>
D	H01L2924/0425	2	5th Group	<no transfer>
D	H01L2924/0426	2	6th Group	<no transfer>
D	H01L2924/0427	2	7th Group	<no transfer>
D	H01L2924/0428	2	8th Group	<no transfer>
D	H01L2924/0429	2	9th Group	<no transfer>
D	H01L2924/044	2	10th Group	<no transfer>
D	H01L2924/0441	2	11th Group	<no transfer>
D	H01L2924/0442	2	12th Group	<no transfer>
D	H01L2924/0443	2	13th Group	<no transfer>
D	H01L2924/0444	2	14th Group	<no transfer>
D	H01L2924/0445	2	Lanthanides	<no transfer>
D	H01L2924/0446	2	Actinides	<no transfer>
D	H01L2924/0449	2	being a combination of two or more materials provided in the groups H01L2924/0421 - H01L2924/0446	<no transfer>
D	H01L2924/04491	2	having a monocrystalline microstructure	<no transfer>

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D	H01L2924/04492	2	having a polycrystalline microstructure	<no transfer>
D	H01L2924/04494	2	having an amorphous microstructure, i.e. glass	<no transfer>
D	H01L2924/045	1	Carbides composed of metals from groups of the periodic table	<no transfer>
D	H01L2924/0451	2	1st Group	<no transfer>
D	H01L2924/0452	2	2nd Group	<no transfer>
D	H01L2924/0453	2	3rd Group	<no transfer>
D	H01L2924/0454	2	4th Group	<no transfer>
D	H01L2924/04541	3	TiC	<no transfer>
D	H01L2924/0455	2	5th Group	<no transfer>
D	H01L2924/0456	2	6th Group	<no transfer>
D	H01L2924/04563	3	WC	<no transfer>
D	H01L2924/0457	2	7th Group	<no transfer>
D	H01L2924/0458	2	8th Group	<no transfer>
D	H01L2924/0459	2	9th Group	<no transfer>
D	H01L2924/046	2	10th Group	<no transfer>
D	H01L2924/0461	2	11th Group	<no transfer>
D	H01L2924/0462	2	12th Group	<no transfer>
D	H01L2924/0463	2	13th Group	<no transfer>
D	H01L2924/0464	2	14th Group	<no transfer>
D	H01L2924/04642	3	SiC	<no transfer>
D	H01L2924/0465	2	Lanthanides	<no transfer>
D	H01L2924/0466	2	Actinides	<no transfer>
D	H01L2924/0469	2	being a combination of two or more materials provided in the groups H01L2924/0451 - H01L2924/0466	<no transfer>
D	H01L2924/04691	2	having a monocrystalline microstructure	<no transfer>
D	H01L2924/04692	2	having a polycrystalline microstructure	<no transfer>
D	H01L2924/04694	2	having an amorphous microstructure, i.e. glass	<no transfer>
D	H01L2924/047	1	Silicides composed of metals from groups of the periodic table	<no transfer>
D	H01L2924/0471	2	1st Group	<no transfer>
D	H01L2924/0472	2	2nd Group	<no transfer>
D	H01L2924/0473	2	3rd Group	<no transfer>
D	H01L2924/0474	2	4th Group	<no transfer>
D	H01L2924/0475	2	5th Group	<no transfer>
D	H01L2924/0476	2	6th Group	<no transfer>
D	H01L2924/0477	2	7th Group	<no transfer>
D	H01L2924/0478	2	8th Group	<no transfer>
D	H01L2924/0479	2	9th Group	<no transfer>

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D	H01L2924/048	2	10th Group	<no transfer>
D	H01L2924/0481	2	11th Group	<no transfer>
D	H01L2924/0482	2	12th Group	<no transfer>
D	H01L2924/0483	2	13th Group	<no transfer>
D	H01L2924/0484	2	14th Group	<no transfer>
D	H01L2924/0485	2	Lanthanides	<no transfer>
D	H01L2924/0486	2	Actinides	<no transfer>
D	H01L2924/0489	2	being a combination of two or more materials provided in the groups H01L2924/0471 - H01L2924/0486	<no transfer>
D	H01L2924/04891	2	having a monocrystalline microstructure	<no transfer>
D	H01L2924/04892	2	having a polycrystalline microstructure	<no transfer>
D	H01L2924/04894	2	having an amorphous microstructure, i.e. glass	<no transfer>
D	H01L2924/049	1	Nitrides composed of metals from groups of the periodic table	<no transfer>
D	H01L2924/0491	2	1st Group	<no transfer>
D	H01L2924/0492	2	2nd Group	<no transfer>
D	H01L2924/0493	2	3rd Group	<no transfer>
D	H01L2924/0494	2	4th Group	<no transfer>
D	H01L2924/04941	3	TiN	<no transfer>
D	H01L2924/0495	2	5th Group	<no transfer>
D	H01L2924/04953	3	TaN	<no transfer>
D	H01L2924/0496	2	6th Group	<no transfer>
D	H01L2924/0497	2	7th Group	<no transfer>
D	H01L2924/0498	2	8th Group	<no transfer>
D	H01L2924/0499	2	9th Group	<no transfer>
D	H01L2924/05	2	10th Group	<no transfer>
D	H01L2924/0501	2	11th Group	<no transfer>
D	H01L2924/0502	2	12th Group	<no transfer>
D	H01L2924/0503	2	13th Group	<no transfer>
D	H01L2924/05032	3	AlN	<no transfer>
D	H01L2924/0504	2	14th Group	<no transfer>
D	H01L2924/05042	3	Si ₃ N ₄	<no transfer>
D	H01L2924/0505	2	Lanthanides	<no transfer>
D	H01L2924/0506	2	Actinides	<no transfer>
D	H01L2924/0509	2	being a combination of two or more materials provided in the groups H01L2924/0491 - H01L2924/0506	<no transfer>
D	H01L2924/05091	2	having a monocrystalline microstructure	<no transfer>
D	H01L2924/05092	2	having a polycrystalline microstructure	<no transfer>

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D	H01L2924/05094	2	having an amorphous microstructure, i.e. glass	<no transfer>
D	H01L2924/051	1	Phosphides composed of metals from groups of the periodic table	<no transfer>
D	H01L2924/0511	2	1st Group	<no transfer>
D	H01L2924/0512	2	2nd Group	<no transfer>
D	H01L2924/0513	2	3rd Group	<no transfer>
D	H01L2924/0514	2	4th Group	<no transfer>
D	H01L2924/0515	2	5th Group	<no transfer>
D	H01L2924/0516	2	6th Group	<no transfer>
D	H01L2924/0517	2	7th Group	<no transfer>
D	H01L2924/0518	2	8th Group	<no transfer>
D	H01L2924/0519	2	9th Group	<no transfer>
D	H01L2924/052	2	10th Group	<no transfer>
D	H01L2924/0521	2	11th Group	<no transfer>
D	H01L2924/0522	2	12th Group	<no transfer>
D	H01L2924/0523	2	13th Group	<no transfer>
D	H01L2924/0524	2	14th Group	<no transfer>
D	H01L2924/0525	2	Lanthanides	<no transfer>
D	H01L2924/0526	2	Actinides	<no transfer>
D	H01L2924/0529	2	being a combination of two or more materials provided in the groups H01L2924/0511 - H01L2924/0526	<no transfer>
D	H01L2924/05291	2	having a monocrystalline microstructure	<no transfer>
D	H01L2924/05292	2	having a polycrystalline microstructure	<no transfer>
D	H01L2924/05294	2	having an amorphous microstructure, i.e. glass	<no transfer>
D	H01L2924/053	1	Oxides composed of metals from groups of the periodic table	<no transfer>
D	H01L2924/0531	2	1st Group	<no transfer>
D	H01L2924/0532	2	2nd Group	<no transfer>
D	H01L2924/0533	2	3rd Group	<no transfer>
D	H01L2924/0534	2	4th Group	<no transfer>
D	H01L2924/05341	3	TiO ₂	<no transfer>
D	H01L2924/05342	3	ZrO ₂	<no transfer>
D	H01L2924/0535	2	5th Group	<no transfer>
D	H01L2924/0536	2	6th Group	<no transfer>
D	H01L2924/0537	2	7th Group	<no transfer>
D	H01L2924/0538	2	8th Group	<no transfer>
D	H01L2924/05381	3	FeO _x	<no transfer>
D	H01L2924/0539	2	9th Group	<no transfer>
D	H01L2924/054	2	10th Group	<no transfer>

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D	H01L2924/0541	2	11th Group	<no transfer>
D	H01L2924/0542	2	12th Group	<no transfer>
D	H01L2924/0543	2	13th Group	<no transfer>
D	H01L2924/05432	3	Al ₂ O ₃	<no transfer>
D	H01L2924/0544	2	14th Group	<no transfer>
D	H01L2924/05442	3	SiO ₂	<no transfer>
D	H01L2924/0545	2	Lanthanides	<no transfer>
D	H01L2924/0546	2	Actinides	<no transfer>
D	H01L2924/0549	2	being a combination of two or more materials provided in the groups H01L2924/0531 - H01L2924/0546	<no transfer>
D	H01L2924/05491	2	having a monocrystalline microstructure	<no transfer>
D	H01L2924/05492	2	having a polycrystalline microstructure	<no transfer>
D	H01L2924/05494	2	having an amorphous microstructure, i.e. glass	<no transfer>
D	H01L2924/055	1	Chalcogenides other than oxygen i.e. sulfides, selenides and tellurides composed of metals from groups of the periodic table	<no transfer>
D	H01L2924/0551	2	1st Group	<no transfer>
D	H01L2924/0552	2	2nd Group	<no transfer>
D	H01L2924/0553	2	3rd Group	<no transfer>
D	H01L2924/0554	2	4th Group	<no transfer>
D	H01L2924/0555	2	5th Group	<no transfer>
D	H01L2924/0556	2	6th Group	<no transfer>
D	H01L2924/0557	2	7th Group	<no transfer>
D	H01L2924/0558	2	8th Group	<no transfer>
D	H01L2924/0559	2	9th Group	<no transfer>
D	H01L2924/056	2	10th Group	<no transfer>
D	H01L2924/0561	2	11th Group	<no transfer>
D	H01L2924/0562	2	12th Group	<no transfer>
D	H01L2924/0563	2	13th Group	<no transfer>
D	H01L2924/0564	2	14th Group	<no transfer>
D	H01L2924/0565	2	Lanthanides	<no transfer>
D	H01L2924/0566	2	Actinides	<no transfer>
D	H01L2924/0569	2	being a combination of two or more materials provided in the groups H01L2924/0551 - H01L2924/0566	<no transfer>
D	H01L2924/05691	2	having a monocrystalline microstructure	<no transfer>
D	H01L2924/05692	2	having a polycrystalline microstructure	<no transfer>
D	H01L2924/05694	2	having an amorphous microstructure, i.e. glass	<no transfer>
D	H01L2924/057	1	Halides composed of metals from groups of the periodic table	<no transfer>

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D	H01L2924/0571	2	1st Group	<no transfer>
D	H01L2924/0572	2	2nd Group	<no transfer>
D	H01L2924/0573	2	3rd Group	<no transfer>
D	H01L2924/0574	2	4th Group	<no transfer>
D	H01L2924/0575	2	5th Group	<no transfer>
D	H01L2924/0576	2	6th Group	<no transfer>
D	H01L2924/0577	2	7th Group	<no transfer>
D	H01L2924/0578	2	8th Group	<no transfer>
D	H01L2924/0579	2	9th Group	<no transfer>
D	H01L2924/058	2	10th Group	<no transfer>
D	H01L2924/0581	2	11th Group	<no transfer>
D	H01L2924/0582	2	12th Group	<no transfer>
D	H01L2924/0583	2	13th Group	<no transfer>
D	H01L2924/0584	2	14th Group	<no transfer>
D	H01L2924/0585	2	Lanthanides	<no transfer>
D	H01L2924/0586	2	Actinides	<no transfer>
D	H01L2924/0589	2	being a combination of two or more materials provided in the groups H01L2924/0571 - H01L2924/0586	<no transfer>
D	H01L2924/05891	2	having a monocrystalline microstructure	<no transfer>
D	H01L2924/05892	2	having a polycrystalline microstructure	<no transfer>
D	H01L2924/05894	2	having an amorphous microstructure, i.e. glass	<no transfer>
D	H01L2924/059	1	Being combinations of any of the materials from the groups H01L2924/042 - H01L2924/0584, e.g. oxynitrides	<no transfer>
D	H01L2924/05991	2	having a monocrystalline microstructure	<no transfer>
D	H01L2924/05992	2	having a polycrystalline microstructure	<no transfer>
D	H01L2924/05994	2	having an amorphous microstructure, i.e. glass	<no transfer>
D	H01L2924/06	1	Polymers	<no transfer>
D	H01L2924/061	2	Polyolefin polymer	<no transfer>
D	H01L2924/0615	2	Styrenic polymer	<no transfer>
D	H01L2924/062	2	Halogenated polymer	<no transfer>
D	H01L2924/0625	2	Polyvinyl alcohol	<no transfer>
D	H01L2924/063	2	Polyvinyl acetate	<no transfer>
D	H01L2924/0635	2	Acrylic polymer	<no transfer>
D	H01L2924/064	2	Graft polymer	<no transfer>
D	H01L2924/0645	2	Block copolymer	<no transfer>
D	H01L2924/065	2	ABS	<no transfer>
D	H01L2924/0655	2	Polyacetal	<no transfer>

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D	H01L2924/066	2	Phenolic resin	<no transfer>
D	H01L2924/0665	2	Epoxy resin	<no transfer>
D	H01L2924/067	2	Polyphenylene	<no transfer>
D	H01L2924/0675	2	Polyester	<no transfer>
D	H01L2924/068	2	Polycarbonate	<no transfer>
D	H01L2924/0685	2	Polyether	<no transfer>
D	H01L2924/069	2	Polyurethane	<no transfer>
D	H01L2924/0695	2	Polyamide	<no transfer>
D	H01L2924/07	2	Polyamine or polyimide	<no transfer>
D	H01L2924/07001	3	Polyamine	<no transfer>
D	H01L2924/07025	3	Polyimide	<no transfer>
D	H01L2924/0705	2	Sulfur containing polymer	<no transfer>
D	H01L2924/0715	2	Polysiloxane	<no transfer>
D	H01L2924/078	2	Adhesive characteristics other than chemical	<no transfer>
D	H01L2924/07802	3	not being an ohmic electrical conductor	<no transfer>
D	H01L2924/0781	3	being an ohmic electrical conductor	<no transfer>
D	H01L2924/07811	4	Extrinsic, i.e. with electrical conductive fillers	<no transfer>
D	H01L2924/07812	4	Intrinsic, e.g. polyaniline [PANI]	<no transfer>
D	H01L2924/0782	3	being pressure sensitive	<no transfer>
D	H01L2924/095	1	with a principal constituent of the material being a combination of two or more materials provided in the groups H01L2924/013 - H01L2924/0715	<no transfer>
D	H01L2924/0951	2	Glass epoxy laminates	<no transfer>
D	H01L2924/09511	3	FR-4	<no transfer>
D	H01L2924/09512	3	FR-5	<no transfer>
D	H01L2924/09522	3	G10	<no transfer>
D	H01L2924/09523	3	G11	<no transfer>
D	H01L2924/096	2	Cermets, i.e. composite material composed of ceramic and metallic materials	<no transfer>
D	H01L2924/097	2	Glass-ceramics, e.g. devitrified glass	<no transfer>
D	H01L2924/09701	3	Low temperature co-fired ceramic [LTCC]	<no transfer>
D	H01L2924/10	1	Details of semiconductor or other solid state devices to be connected	<no transfer>
D	H01L2924/1011	2	Structure	<no transfer>
D	H01L2924/1015	2	Shape	<no transfer>
D	H01L2924/10155	3	being other than a cuboid	<no transfer>
D	H01L2924/10156	4	at the periphery	<no transfer>
D	H01L2924/10157	4	at the active surface	<no transfer>
D	H01L2924/10158	4	at the passive surface	<no transfer>
D	H01L2924/1016	3	being a cuboid	<no transfer>

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D	H01L2924/10161	4	with a rectangular active surface	<no transfer>
D	H01L2924/10162	4	with a square active surface	<no transfer>
D	H01L2924/1017	3	being a sphere	<no transfer>
D	H01L2924/102	2	Material of the semiconductor or solid state bodies	<no transfer>
D	H01L2924/1025	3	Semiconducting materials	<no transfer>
D	H01L2924/10251	4	Elemental semiconductors, i.e. Group IV	<no transfer>
D	H01L2924/10252	5	Germanium [Ge]	<no transfer>
D	H01L2924/10253	5	Silicon [Si]	<no transfer>
D	H01L2924/10254	5	Diamond [C]	<no transfer>
D	H01L2924/1026	4	Compound semiconductors	<no transfer>
D	H01L2924/1027	5	IV	<no transfer>
D	H01L2924/10271	6	Silicon-germanium [SiGe]	<no transfer>
D	H01L2924/10272	6	Silicon Carbide [SiC]	<no transfer>
D	H01L2924/1032	5	III-V	<no transfer>
D	H01L2924/10321	6	Aluminium antimonide [AlSb]	<no transfer>
D	H01L2924/10322	6	Aluminium arsenide [AlAs]	<no transfer>
D	H01L2924/10323	6	Aluminium nitride [AlN]	<no transfer>
D	H01L2924/10324	6	Aluminium phosphide [AlP]	<no transfer>
D	H01L2924/10325	6	Boron nitride [BN], e.g. cubic, hexagonal, nanotube	<no transfer>
D	H01L2924/10326	6	Boron phosphide [BP]	<no transfer>
D	H01L2924/10327	6	Boron arsenide [BAs, B ₁₂ As ₂]	<no transfer>
D	H01L2924/10328	6	Gallium antimonide [GaSb]	<no transfer>
D	H01L2924/10329	6	Gallium arsenide [GaAs]	<no transfer>
D	H01L2924/1033	6	Gallium nitride [GaN]	<no transfer>
D	H01L2924/10331	6	Gallium phosphide [GaP]	<no transfer>
D	H01L2924/10332	6	Indium antimonide [InSb]	<no transfer>
D	H01L2924/10333	6	Indium arsenide [InAs]	<no transfer>
D	H01L2924/10334	6	Indium nitride [InN]	<no transfer>
D	H01L2924/10335	6	Indium phosphide [InP]	<no transfer>
D	H01L2924/10336	6	Aluminium gallium arsenide [AlGaAs]	<no transfer>
D	H01L2924/10337	6	Indium gallium arsenide [InGaAs]	<no transfer>
D	H01L2924/10338	6	Indium gallium phosphide [InGaP]	<no transfer>
D	H01L2924/10339	6	Aluminium indium arsenide [AlInAs]	<no transfer>
D	H01L2924/1034	6	Aluminium indium antimonide [AlInSb]	<no transfer>
D	H01L2924/10341	6	Gallium arsenide nitride [GaAsN]	<no transfer>
D	H01L2924/10342	6	Gallium arsenide phosphide [GaAsP]	<no transfer>
D	H01L2924/10343	6	Gallium arsenide antimonide [GaAsSb]	<no transfer>
D	H01L2924/10344	6	Aluminium gallium nitride [AlGaN]	<no transfer>
D	H01L2924/10345	6	Aluminium gallium phosphide [AlGaP]	<no transfer>

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D	H01L2924/10346	6	Indium gallium nitride [InGaN]	<no transfer>
D	H01L2924/10347	6	Indium arsenide antimonide [InAsSb]	<no transfer>
D	H01L2924/10348	6	Indium gallium antimonide [InGaSb]	<no transfer>
D	H01L2924/10349	6	Aluminium gallium indium phosphide [AlGaInP]	<no transfer>
D	H01L2924/1035	6	Aluminium gallium arsenide phosphide [AlGaInP]	<no transfer>
D	H01L2924/10351	6	Indium gallium arsenide phosphide [InGaAsP]	<no transfer>
D	H01L2924/10352	6	Indium gallium arsenide antimonide [InGaAsSb]	<no transfer>
D	H01L2924/10353	6	Indium arsenide antimonide phosphide [InAsSbP]	<no transfer>
D	H01L2924/10354	6	Aluminium indium arsenide phosphide [AlInAsP]	<no transfer>
D	H01L2924/10355	6	Aluminium gallium arsenide nitride [AlGaAsN]	<no transfer>
D	H01L2924/10356	6	Indium gallium arsenide nitride [InGaAsN]	<no transfer>
D	H01L2924/10357	6	Indium aluminium arsenide nitride [InAlAsN]	<no transfer>
D	H01L2924/10358	6	Gallium arsenide antimonide nitride [GaAsSbN]	<no transfer>
D	H01L2924/10359	6	Gallium indium nitride arsenide antimonide [GaInNAsSb]	<no transfer>
D	H01L2924/1036	6	Gallium indium arsenide antimonide phosphide [GaInAsSbP]	<no transfer>
D	H01L2924/1037	5	II-VI	<no transfer>
D	H01L2924/10371	6	Cadmium selenide [CdSe]	<no transfer>
D	H01L2924/10372	6	Cadmium sulfide [CdS]	<no transfer>
D	H01L2924/10373	6	Cadmium telluride [CdTe]	<no transfer>
D	H01L2924/10375	6	Zinc selenide [ZnSe]	<no transfer>
D	H01L2924/10376	6	Zinc sulfide [ZnS]	<no transfer>
D	H01L2924/10377	6	Zinc telluride [ZnTe]	<no transfer>
D	H01L2924/10378	6	Cadmium zinc telluride, i.e. CZT [CdZnTe]	<no transfer>
D	H01L2924/10379	6	Mercury cadmium telluride [HgZnTe]	<no transfer>
D	H01L2924/1038	6	Mercury zinc telluride [HgZnSe]	<no transfer>
D	H01L2924/10381	6	Mercury zinc selenide [HgZnSe]	<no transfer>
D	H01L2924/1042	5	I-VII	<no transfer>
D	H01L2924/10421	6	Cuprous chloride [CuCl]	<no transfer>
D	H01L2924/1047	5	I-VI	<no transfer>
D	H01L2924/10471	6	Copper sulfide [CuS]	<no transfer>
D	H01L2924/1052	5	IV-VI	<no transfer>
D	H01L2924/10521	6	Lead selenide [PbSe]	<no transfer>

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D	H01L2924/10522	6	Lead(II)sulfide [PbS]	<no transfer>
D	H01L2924/10523	6	Lead telluride [PbTe]	<no transfer>
D	H01L2924/10524	6	Tin sulfide [SnS, SnS ₂]	<no transfer>
D	H01L2924/10525	6	Tin telluride [SnTe]	<no transfer>
D	H01L2924/10526	6	Lead tin telluride [PbSnTe]	<no transfer>
D	H01L2924/10527	6	Thallium tin telluride [Tl ₂ SnTe ₅]	<no transfer>
D	H01L2924/10528	6	Thallium germanium telluride [Tl ₂ GeTe ₅]	<no transfer>
D	H01L2924/1057	5	V-VI	<no transfer>
D	H01L2924/10571	6	Bismuth telluride [Bi ₂ Te ₃]	<no transfer>
D	H01L2924/1062	5	II-V	<no transfer>
D	H01L2924/10621	6	Cadmium phosphide [Cd ₃ P ₂]	<no transfer>
D	H01L2924/10622	6	Cadmium arsenide [Cd ₃ As ₂]	<no transfer>
D	H01L2924/10623	6	Cadmium antimonide [Cd ₃ Sb ₂]	<no transfer>
D	H01L2924/10624	6	Zinc phosphide [Zn ₃ P ₂]	<no transfer>
D	H01L2924/10625	6	Zinc arsenide [Zn ₃ As ₂]	<no transfer>
D	H01L2924/10626	6	Zinc antimonide [Zn ₃ Sb ₂]	<no transfer>
D	H01L2924/1067	5	Oxide	<no transfer>
D	H01L2924/10671	6	Titanium dioxide, anatase, rutile, brookite [TiO ₂]	<no transfer>
D	H01L2924/10672	6	Copper(I)oxide [Cu ₂ O]	<no transfer>
D	H01L2924/10673	6	Copper(II)oxide [CuO]	<no transfer>
D	H01L2924/10674	6	Uranium dioxide [UO ₂]	<no transfer>
D	H01L2924/10675	6	Uranium trioxide [UO ₃]	<no transfer>
D	H01L2924/10676	6	Bismuth trioxide [Bi ₂ O ₃]	<no transfer>
D	H01L2924/10677	6	Tin dioxide [SnO ₂]	<no transfer>
D	H01L2924/10678	6	Barium titanate [BaTiO ₃]	<no transfer>
D	H01L2924/10679	6	Strontium titanate [SrTiO ₃]	<no transfer>
D	H01L2924/1068	6	Lithium niobate [LiNbO ₃]	<no transfer>
D	H01L2924/10681	6	Lanthanum copper oxide [La ₂ CuO ₄]	<no transfer>
D	H01L2924/1072	5	Layered	<no transfer>
D	H01L2924/10721	6	Lead(II)iodide [PbI ₂]	<no transfer>
D	H01L2924/10722	6	Molybdenum disulfide [MoS ₂]	<no transfer>
D	H01L2924/10723	6	Gallium selenide [GaSe]	<no transfer>
D	H01L2924/10724	6	Tin sulfide [SnS]	<no transfer>
D	H01L2924/10725	6	Bismuth sulfide [Bi ₂ S ₃]	<no transfer>
D	H01L2924/1077	5	Magnetic diluted [DMS]	<no transfer>
D	H01L2924/10771	6	Gallium manganese arsenide [GaMnAs]	<no transfer>
D	H01L2924/10772	6	Indium manganese arsenide [InMnAs]	<no transfer>
D	H01L2924/10773	6	Cadmium manganese telluride [CdMnTe]	<no transfer>
D	H01L2924/10774	6	Lead manganese telluride [PbMnTe]	<no transfer>

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D	H01L2924/10775	6	Lanthanum calcium manganate [La _{0.7} Ca _{0.3} MnO ₃]	<no transfer>
D	H01L2924/10776	6	Iron(II)oxide [FeO]	<no transfer>
D	H01L2924/10777	6	Nickel(II)oxide [NiO]	<no transfer>
D	H01L2924/10778	6	Europium(II)oxide [EuO]	<no transfer>
D	H01L2924/10779	6	Europium(II)sulfide [EuS]	<no transfer>
D	H01L2924/1078	6	Chromium(III)bromide [CrBr ₃]	<no transfer>
D	H01L2924/1082	5	Other	<no transfer>
D	H01L2924/10821	6	Copper indium gallium selenide, CIGS [Cu[In,Ga]Se ₂]	<no transfer>
D	H01L2924/10822	6	Copper zinc tin sulfide, CZTS [Cu ₂ ZnSnS ₄]	<no transfer>
D	H01L2924/10823	6	Copper indium selenide, CIS [CuInSe ₂]	<no transfer>
D	H01L2924/10824	6	Silver gallium sulfide [AgGaS ₂]	<no transfer>
D	H01L2924/10825	6	Zinc silicon phosphide [ZnSiP ₂]	<no transfer>
D	H01L2924/10826	6	Arsenic selenide [As ₂ S ₃]	<no transfer>
D	H01L2924/10827	6	Platinum silicide [PtSi]	<no transfer>
D	H01L2924/10828	6	Bismuth(III)iodide [BiI ₃]	<no transfer>
D	H01L2924/10829	6	Mercury(II)iodide [HgI ₂]	<no transfer>
D	H01L2924/1083	6	Thallium(I)bromide [TlBr]	<no transfer>
D	H01L2924/10831	6	Selenium [Se]	<no transfer>
D	H01L2924/10832	6	Silver sulfide [Ag ₂ S]	<no transfer>
D	H01L2924/10833	6	Iron disulfide [FeS ₂]	<no transfer>
D	H01L2924/11	2	Device type	<no transfer>
D	H01L2924/12	3	Passive devices, e.g. 2 terminal devices	<no transfer>
D	H01L2924/1203	4	Rectifying Diode	<no transfer>
D	H01L2924/12031	5	PIN diode	<no transfer>
D	H01L2924/12032	5	Schottky diode	<no transfer>
D	H01L2924/12033	5	Gunn diode	<no transfer>
D	H01L2924/12034	5	Varactor	<no transfer>
D	H01L2924/12035	5	Zener diode	<no transfer>
D	H01L2924/12036	5	PN diode	<no transfer>
D	H01L2924/12037	5	Cat's whisker diode	<no transfer>
D	H01L2924/12038	5	Point contact	<no transfer>
D	H01L2924/1204	4	Optical Diode	<no transfer>
D	H01L2924/12041	5	LED	<no transfer>
D	H01L2924/12042	5	LASER	<no transfer>
D	H01L2924/12043	5	Photo diode	<no transfer>
D	H01L2924/12044	5	OLED	<no transfer>
D	H01L2924/1205	4	Capacitor	<no transfer>
D	H01L2924/1206	4	Inductor	<no transfer>
D	H01L2924/1207	4	Resistor	<no transfer>

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D	H01L2924/13	3	Discrete devices, e.g. 3 terminal devices	<no transfer>
D	H01L2924/1301	4	Thyristor	<no transfer>
D	H01L2924/13011	5	Anode Gate Thyristor [AGT]	<no transfer>
D	H01L2924/13013	5	Bidirectional Control Thyristor [BCT]	<no transfer>
D	H01L2924/13014	5	Breakover Diode [BOD]	<no transfer>
D	H01L2924/13015	5	DIAC - Bidirectional trigger device	<no transfer>
D	H01L2924/13016	5	Dynistor - Unidirectional switching device	<no transfer>
D	H01L2924/13017	5	Shockley diode - Unidirectional trigger and switching device	<no transfer>
D	H01L2924/13018	5	SIDAC - Bidirectional switching device	<no transfer>
D	H01L2924/13019	5	Trisil, SIDACtor - Bidirectional protection devices	<no transfer>
D	H01L2924/1302	5	GTO - Gate Turn-Off thyristor	<no transfer>
D	H01L2924/13021	6	DB-GTO - Distributed Buffer Gate Turn-Off thyristor	<no transfer>
D	H01L2924/13022	6	MA-GTO - Modified Anode Gate Turn-Off thyristor	<no transfer>
D	H01L2924/13023	5	IGCT - Integrated Gate Commutated Thyristor	<no transfer>
D	H01L2924/13024	5	LASCR - Light Activated SCR, or LTT - Light triggered thyristor	<no transfer>
D	H01L2924/13025	5	Light Activated Semiconducting Switch [LASS]	<no transfer>
D	H01L2924/13026	5	MCT - MOSFET Controlled Thyristor - It contains two additional FET structures for on/off control	<no transfer>
D	H01L2924/13027	5	BRT - Base Resistance Controlled Thyristor	<no transfer>
D	H01L2924/13028	5	RCT - Reverse Conducting Thyristor	<no transfer>
D	H01L2924/13029	5	PUT or PUJT - Programmable Unijunction Transistor - A thyristor with gate on n-type layer near to the anode used as a functional replacement for unijunction transistor	<no transfer>
D	H01L2924/1303	5	SCS - Silicon Controlled Switch or Thyristor Tetrode - A thyristor with both cathode and anode gates	<no transfer>
D	H01L2924/13032	5	SITh - Static Induction Thyristor, or FCTh - Field Controlled Thyristor - containing a gate structure that can shut down anode current flow	<no transfer>
D	H01L2924/13033	5	TRIAC - Triode for Alternating Current - A bidirectional switching device containing two thyristor structures with common gate contact	<no transfer>
D	H01L2924/13034	5	Silicon Controlled Rectifier [SCR]	<no transfer>
D	H01L2924/13035	6	Asymmetrical SCR [ASCR]	<no transfer>
D	H01L2924/1304	4	Transistor	<no transfer>
D	H01L2924/1305	5	Bipolar Junction Transistor [BJT]	<no transfer>

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D	H01L2924/13051	6	Heterojunction bipolar transistor [HBT]	<no transfer>
D	H01L2924/13052	6	Schottky transistor	<no transfer>
D	H01L2924/13053	6	Avalanche transistor	<no transfer>
D	H01L2924/13054	6	Darlington transistor	<no transfer>
D	H01L2924/13055	6	Insulated gate bipolar transistor [IGBT]	<no transfer>
D	H01L2924/13056	6	Photo transistor	<no transfer>
D	H01L2924/1306	5	Field-effect transistor [FET]	<no transfer>
D	H01L2924/13061	6	Carbon nanotube field-effect transistor [CNFET]	<no transfer>
D	H01L2924/13062	6	Junction field-effect transistor [JFET]	<no transfer>
D	H01L2924/13063	6	Metal-Semiconductor Field-Effect Transistor [MESFET]	<no transfer>
D	H01L2924/13064	6	High Electron Mobility Transistor [HEMT, HFET [heterostructure FET], MODFET]	<no transfer>
D	H01L2924/13066	6	Inverted-T field effect transistor [ITFET]	<no transfer>
D	H01L2924/13067	6	FinFET, source/drain region shapes fins on the silicon surface	<no transfer>
D	H01L2924/13068	6	Fast-reverse epitaxial diode field-effect transistor [FREDFET]	<no transfer>
D	H01L2924/13069	6	Thin film transistor [TFT]	<no transfer>
D	H01L2924/1307	6	Organic Field-Effect Transistor [OFET]	<no transfer>
D	H01L2924/13071	6	Ballistic transistor	<no transfer>
D	H01L2924/13072	6	Sensor FET	<no transfer>
D	H01L2924/13073	7	ion-sensitive field-effect transistor [ISFET]	<no transfer>
D	H01L2924/13074	7	Electrolyte-oxide-semiconductor field effect transistor [EOSFET], e.g. Neurochip	<no transfer>
D	H01L2924/13075	7	Deoxyribonucleic acid field-effect transistor [DNAFET]	<no transfer>
D	H01L2924/13076	7	DEPFET	<no transfer>
D	H01L2924/13078	6	Unijunction transistors	<no transfer>
D	H01L2924/13079	6	Single-electron transistors [SET]	<no transfer>
D	H01L2924/1308	6	Nanofluidic transistor	<no transfer>
D	H01L2924/13081	6	Multigate devices	<no transfer>
D	H01L2924/13082	7	Tetrode transistor	<no transfer>
D	H01L2924/13083	7	Pentode transistor	<no transfer>
D	H01L2924/13084	7	Trigate transistor	<no transfer>
D	H01L2924/13085	7	Dual gate FETs	<no transfer>
D	H01L2924/13086	6	Junctionless Nanowire Transistor [JNT]	<no transfer>
D	H01L2924/13087	6	Vertical-Slit Field-Effect Transistor [VeSFET]	<no transfer>
D	H01L2924/13088	6	Graphene Nanoribbon Field-Effect Transistor [GNRFET]	<no transfer>

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D	H01L2924/13089	6	Nanoparticle Organic Memory Field-Effect Transistor [NOMFET]	<no transfer>
D	H01L2924/1309	6	Modulation-Doped Field Effect Transistor [MODFET]	<no transfer>
D	H01L2924/13091	6	Metal-Oxide-Semiconductor Field-Effect Transistor [MOSFET]	<no transfer>
D	H01L2924/13092	7	Dual Gate Metal-Oxide-Semiconductor Field-Effect Transistor [DGMOSFET]	<no transfer>
D	H01L2924/14	3	Integrated circuits	<no transfer>
D	H01L2924/141	4	Analog devices	<no transfer>
D	H01L2924/142	5	HF devices	<no transfer>
D	H01L2924/1421	6	RF devices	<no transfer>
D	H01L2924/14211	7	Voltage-controlled oscillator [VCO]	<no transfer>
D	H01L2924/14215	7	Low-noise amplifier [LNA]	<no transfer>
D	H01L2924/1422	7	Mixer	<no transfer>
D	H01L2924/14221	8	Electronic mixer	<no transfer>
D	H01L2924/14222	8	Frequency mixer	<no transfer>
D	H01L2924/1423	5	Monolithic Microwave Integrated Circuit [MMIC]	<no transfer>
D	H01L2924/1424	5	Operational amplifier	<no transfer>
D	H01L2924/1425	5	Converter	<no transfer>
D	H01L2924/14251	6	Frequency converter	<no transfer>
D	H01L2924/14252	6	Voltage converter	<no transfer>
D	H01L2924/14253	6	Digital-to-analog converter [DAC]	<no transfer>
D	H01L2924/1426	5	Driver	<no transfer>
D	H01L2924/1427	5	Voltage regulator [VR]	<no transfer>
D	H01L2924/143	4	Digital devices	<no transfer>
D	H01L2924/1431	5	Logic devices	<no transfer>
D	H01L2924/1432	5	Central processing unit [CPU]	<no transfer>
D	H01L2924/1433	5	Application-specific integrated circuit [ASIC]	<no transfer>
D	H01L2924/14335	5	Digital signal processor [DSP]	<no transfer>
D	H01L2924/1434	5	Memory	<no transfer>
D	H01L2924/1435	6	Random access memory [RAM]	<no transfer>
D	H01L2924/1436	7	Dynamic random-access memory [DRAM]	<no transfer>
D	H01L2924/14361	8	Synchronous dynamic random access memory [SDRAM]	<no transfer>
D	H01L2924/14362	9	RAS Only Refresh [ROR]	<no transfer>
D	H01L2924/14363	9	CAS before RAS refresh [CBR]	<no transfer>
D	H01L2924/14364	8	Multibank DRAM [MDRAM]	<no transfer>
D	H01L2924/14365	8	Video DRAM [VRAM]	<no transfer>
D	H01L2924/14366	8	Window DRAM [WRAM]	<no transfer>
D	H01L2924/14367	8	Fast page mode DRAM [FPM DRAM]	<no transfer>

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D	H01L2924/14368	8	Extended data out DRAM [EDO DRAM]	<no transfer>
D	H01L2924/14369	8	Burst EDO DRAM [BEDO DRAM]	<no transfer>
D	H01L2924/1437	7	Static random-access memory [SRAM]	<no transfer>
D	H01L2924/1438	7	Flash memory	<no transfer>
D	H01L2924/1441	7	Ferroelectric RAM [FeRAM or FRAM]	<no transfer>
D	H01L2924/1442	7	Synchronous graphics RAM [SGRAM]	<no transfer>
D	H01L2924/1443	7	Non-volatile random-access memory [NVRAM]	<no transfer>
D	H01L2924/1444	7	PBRAM	<no transfer>
D	H01L2924/145	6	Read-only memory [ROM]	<no transfer>
D	H01L2924/1451	7	EPROM	<no transfer>
D	H01L2924/14511	8	EEPROM	<no transfer>
D	H01L2924/1453	7	PROM	<no transfer>
D	H01L2924/146	2	Mixed devices	<no transfer>
D	H01L2924/1461	3	MEMS	<no transfer>
D	H01L2924/15	1	Details of package parts other than the semiconductor or other solid state devices to be connected	<no transfer>
D	H01L2924/151	2	Die mounting substrate	<administrative transfer to H10W 70/60>
D	H01L2924/1511	3	Structure	<administrative transfer to H10W 70/60>
D	H01L2924/1515	3	Shape	<administrative transfer to H10W 70/60>
D	H01L2924/15151	4	the die mounting substrate comprising an aperture, e.g. for underfilling, outgassing, window type wire connections	<administrative transfer to H10W 70/681>
D	H01L2924/15153	4	the die mounting substrate comprising a recess for hosting the device	<administrative transfer to H10W 70/682>
D	H01L2924/15155	5	the shape of the recess being other than a cuboid	<administrative transfer to H10W 70/682>
D	H01L2924/15156	6	Side view	<administrative transfer to H10W 70/682>
D	H01L2924/15157	6	Top view	<administrative transfer to H10W 70/682>
D	H01L2924/15158	4	the die mounting substrate being other than a cuboid	<no transfer>
D	H01L2924/15159	5	Side view	<no transfer>
D	H01L2924/15162	5	Top view	<no transfer>
D	H01L2924/15165	3	Monolayer substrate	<no transfer>
D	H01L2924/1517	3	Multilayer substrate	<administrative transfer to H10W 70/685>
D	H01L2924/15172	4	Fan-out arrangement of the internal vias	<administrative transfer to H10W 70/655>

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D	H01L2924/15173	5	in a single layer of the multilayer substrate	<administrative transfer to H10W 70/655>
D	H01L2924/15174	5	in different layers of the multilayer substrate	<administrative transfer to H10W 70/655>
D	H01L2924/15182	4	Fan-in arrangement of the internal vias	<administrative transfer to H10W 70/656>
D	H01L2924/15183	5	in a single layer of the multilayer substrate	<administrative transfer to H10W 70/656>
D	H01L2924/15184	5	in different layers of the multilayer substrate	<administrative transfer to H10W 70/656>
D	H01L2924/15192	4	Resurf arrangement of the internal vias	<administrative transfer to H10W 70/63>
D	H01L2924/152	3	Disposition	<no transfer>
D	H01L2924/153	3	Connection portion	<no transfer>
D	H01L2924/1531	4	the connection portion being formed only on the surface of the substrate opposite to the die mounting surface	<no transfer>
D	H01L2924/15311	5	being a ball array, e.g. BGA	<no transfer>
D	H01L2924/15312	5	being a pin array, e.g. PGA	<no transfer>
D	H01L2924/15313	5	being a land array, e.g. LGA	<no transfer>
D	H01L2924/1532	4	the connection portion being formed on the die mounting surface of the substrate	<no transfer>
D	H01L2924/15321	5	being a ball array, e.g. BGA	<no transfer>
D	H01L2924/15322	5	being a pin array, e.g. PGA	<no transfer>
D	H01L2924/15323	5	being a land array, e.g. LGA	<no transfer>
D	H01L2924/1533	5	the connection portion being formed both on the die mounting surface of the substrate and outside the die mounting surface of the substrate	<no transfer>
D	H01L2924/15331	6	being a ball array, e.g. BGA	<no transfer>
D	H01L2924/15332	6	being a pin array, e.g. PGA	<no transfer>
D	H01L2924/15333	6	being a land array, e.g. LGA	<no transfer>
D	H01L2924/156	3	Material	<no transfer>
D	H01L2924/157	4	with a principal constituent of the material being a metal or a metalloid, e.g. boron [B], silicon [Si], germanium [Ge], arsenic [As], antimony [Sb], tellurium [Te] and polonium [Po], and alloys thereof	<no transfer>
D	H01L2924/15701	5	the principal constituent melting at a temperature of less than 400 C	<no transfer>
D	H01L2924/15717	5	the principal constituent melting at a temperature of greater than or equal to 400 C and less than 950 C	<no transfer>
D	H01L2924/15724	6	Aluminium [Al] as principal constituent	<no transfer>

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D	H01L2924/15738	5	the principal constituent melting at a temperature of greater than or equal to 950 C and less than 1550 C	<no transfer>
D	H01L2924/15747	6	Copper [Cu] as principal constituent	<no transfer>
D	H01L2924/1576	6	Iron [Fe] as principal constituent	<no transfer>
D	H01L2924/15763	5	the principal constituent melting at a temperature of greater than 1550 C	<no transfer>
D	H01L2924/15786	4	with a principal constituent of the material being a non metallic, non metalloid inorganic material	<no transfer>
D	H01L2924/15787	5	Ceramics, e.g. crystalline carbides, nitrides or oxides	<no transfer>
D	H01L2924/15788	5	Glasses, e.g. amorphous oxides, nitrides or fluorides	<no transfer>
D	H01L2924/1579	4	with a principal constituent of the material being a polymer, e.g. polyester, phenolic based polymer, epoxy	<no transfer>
D	H01L2924/15791	5	The principal constituent being an elastomer, e.g. silicones, isoprene, neoprene	<no transfer>
D	H01L2924/15793	4	with a principal constituent of the material being a solid not provided for in groups H01L2924/157 - H01L2924/15791, e.g. allotropes of carbon, fullerene, graphite, carbon-nanotubes, diamond	<no transfer>
D	H01L2924/15798	4	with a principal constituent of the material being a combination of two or more materials in the form of a matrix with a filler, i.e. being a hybrid material, e.g. segmented structures, foams	<no transfer>
D	H01L2924/161	2	Cap	<administrative transfer to H10W 76/10>
D	H01L2924/1611	3	Structure	<administrative transfer to H10W 76/10>
D	H01L2924/1615	3	Shape	<administrative transfer to H10W 76/12>
D	H01L2924/16151	4	Cap comprising an aperture, e.g. for pressure control, encapsulation	<no transfer>
D	H01L2924/16152	4	Cap comprising a cavity for hosting the device, e.g. U-shaped cap	<no transfer>
D	H01L2924/16153	5	Cap enclosing a plurality of side-by-side cavities [e.g. E-shaped cap]	<no transfer>
D	H01L2924/1616	5	Cavity shape	<no transfer>
D	H01L2924/1617	5	Cavity coating	<no transfer>
D	H01L2924/16171	6	Material	<no transfer>
D	H01L2924/16172	7	with a principal constituent of the material being a metal or a metalloid, e.g. boron [B], silicon [Si], germanium [Ge], arsenic [As],	<no transfer>

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			antimony [Sb], tellurium [Te] and polonium [Po], and alloys thereof	
D	H01L2924/16173	7	with a principal constituent of the material being a non metallic, non metalloid inorganic material	<no transfer>
D	H01L2924/16174	8	Ceramics, e.g. crystalline carbides, nitrides or oxides	<no transfer>
D	H01L2924/16175	8	Glasses, e.g. amorphous oxides, nitrides or fluorides	<no transfer>
D	H01L2924/16176	7	with a principal constituent of the material being a polymer, e.g. polyester, phenolic based polymer, epoxy	<no transfer>
D	H01L2924/16177	8	The principal constituent being an elastomer, e.g. silicones, isoprene, neoprene	<no transfer>
D	H01L2924/16178	7	with a principal constituent of the material being a solid not provided for in groups H01L2924/157 - H01L2924/15791, e.g. allotropes of carbon, fullerene, graphite, carbon-nanotubes, diamond	<no transfer>
D	H01L2924/16179	7	with a principal constituent of the material being a combination of two or more materials in the form of a matrix with a filler, i.e. being a hybrid material, e.g. segmented structures, foams	<no transfer>
D	H01L2924/1619	5	Cavity coating shape	<no transfer>
D	H01L2924/16195	4	Flat cap [not enclosing an internal cavity]	<no transfer>
D	H01L2924/16196	4	Cap forming a cavity, e.g. being a curved metal foil	<no transfer>
D	H01L2924/162	3	Disposition	<no transfer>
D	H01L2924/16235	4	Connecting to a semiconductor or solid-state bodies, i.e. cap-to-chip	<no transfer>
D	H01L2924/16251	4	Connecting to an item not being a semiconductor or solid-state body, e.g. cap-to-substrate	<no transfer>
D	H01L2924/1626	4	Cap-in-cap assemblies	<no transfer>
D	H01L2924/1627	4	stacked type assemblies, e.g. stacked multi-cavities	<no transfer>
D	H01L2924/163	3	Connection portion, e.g. seal	<administrative transfer to H10W 76/60>
D	H01L2924/1631	4	Structure	<administrative transfer to H10W 76/60>
D	H01L2924/16315	4	Shape	<administrative transfer to H10W 76/63>
D	H01L2924/1632	4	Disposition	<administrative transfer to H10W 76/63>
D	H01L2924/164	4	Material	<administrative transfer to H10W 76/67>

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D	H01L2924/165	5	with a principal constituent of the material being a metal or a metalloid, e.g. boron [B], silicon [Si], germanium [Ge], arsenic [As], antimony [Sb], tellurium [Te] and polonium [Po], and alloys thereof	<administrative transfer to H10W 76/67>
D	H01L2924/16586	5	with a principal constituent of the material being a non metallic, non metalloid inorganic material	<administrative transfer to H10W 76/67>
D	H01L2924/16587	6	Ceramics, e.g. crystalline carbides, nitrides or oxides	<administrative transfer to H10W 76/67>
D	H01L2924/16588	6	Glasses, e.g. amorphous oxides, nitrides or fluorides	<administrative transfer to H10W 76/67>
D	H01L2924/1659	5	with a principal constituent of the material being a polymer, e.g. polyester, phenolic based polymer, epoxy	<administrative transfer to H10W 76/67>
D	H01L2924/16593	5	with a principal constituent of the material being a solid not provided for in groups H01L2924/157 - H01L2924/15791, e.g. allotropes of carbon, fullerene, graphite, carbon-nanotubes, diamond	<administrative transfer to H10W 76/67>
D	H01L2924/16598	5	with a principal constituent of the material being a combination of two or more materials in the form of a matrix with a filler, i.e. being a hybrid material, e.g. segmented structures, foams	<administrative transfer to H10W 76/67>
D	H01L2924/166	3	Material	<administrative transfer to H10W 76/17>
D	H01L2924/167	4	with a principal constituent of the material being a metal or a metalloid, e.g. boron [B], silicon [Si], germanium [Ge], arsenic [As], antimony [Sb], tellurium [Te] and polonium [Po], and alloys thereof	<administrative transfer to H10W 76/17>
D	H01L2924/16701	5	the principal constituent melting at a temperature of less than 400 C	<administrative transfer to H10W 76/17>
D	H01L2924/16717	5	the principal constituent melting at a temperature of greater than or equal to 400 C and less than 950 C	<administrative transfer to H10W 76/17>
D	H01L2924/16724	6	Aluminium [Al] as principal constituent	<administrative transfer to H10W 76/17>
D	H01L2924/16738	5	the principal constituent melting at a temperature of greater than or equal to 950 C and less than 1550 C	<administrative transfer to H10W 76/17>
D	H01L2924/16747	6	Copper [Cu] as principal constituent	<administrative transfer to H10W 76/17>
D	H01L2924/1676	6	Iron [Fe] as principal constituent	<administrative transfer to H10W 76/17>
D	H01L2924/16763	5	the principal constituent melting at a temperature of greater than 1550 C	<administrative transfer to H10W 76/17>

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D	H01L2924/16786	4	with a principal constituent of the material being a non metallic, non metalloid inorganic material	<administrative transfer to H10W 76/18>
D	H01L2924/16787	5	Ceramics, e.g. crystalline carbides, nitrides or oxides	<administrative transfer to H10W 76/18>
D	H01L2924/16788	5	Glasses, e.g. amorphous oxides, nitrides or fluorides	<administrative transfer to H10W 76/18>
D	H01L2924/1679	4	with a principal constituent of the material being a polymer, e.g. polyester, phenolic based polymer, epoxy	<administrative transfer to H10W 76/18>
D	H01L2924/16791	5	The principal constituent being an elastomer, e.g. silicones, isoprene, neoprene	<administrative transfer to H10W 76/18>
D	H01L2924/16793	4	with a principal constituent of the material being a solid not provided for in groups H01L2924/167 - H01L2924/16791, e.g. allotropes of carbon, fullerene, graphite, carbon-nanotubes, diamond	<no transfer>
D	H01L2924/16798	4	with a principal constituent of the material being a combination of two or more materials in the form of a matrix with a filler, i.e. being a hybrid material, e.g. segmented structures, foams	<no transfer>
D	H01L2924/171	2	Frame	<administrative transfer to H10W 76/10>
D	H01L2924/1711	3	Structure	<administrative transfer to H10W 76/10>
D	H01L2924/1715	3	Shape	<administrative transfer to H10W 76/12>
D	H01L2924/17151	4	Frame comprising an aperture, e.g. for pressure control, encapsulation	<administrative transfer to H10W 76/167>
D	H01L2924/172	3	Disposition	<administrative transfer to H10W 76/10>
D	H01L2924/173	3	Connection portion, e.g. seal	<administrative transfer to H10W 76/60>
D	H01L2924/176	3	Material	<administrative transfer to H10W 76/17>
D	H01L2924/177	4	with a principal constituent of the material being a metal or a metalloid, e.g. boron [B], silicon [Si], germanium [Ge], arsenic [As], antimony [Sb], tellurium [Te] and polonium [Po], and alloys thereof	<administrative transfer to H10W 76/17>
D	H01L2924/17701	5	the principal constituent melting at a temperature of less than 400 C	<administrative transfer to H10W 76/17>
D	H01L2924/17717	5	the principal constituent melting at a temperature of greater than or equal to 400 C and less than 950 C	<administrative transfer to H10W 76/17>
D	H01L2924/17724	6	Aluminium [Al] as principal constituent	<administrative transfer to H10W 76/17>

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D	H01L2924/17738	5	the principal constituent melting at a temperature of greater than or equal to 950 C and less than 1550 C	<administrative transfer to H10W 76/17>
D	H01L2924/17747	6	Copper [Cu] as principal constituent	<administrative transfer to H10W 76/17>
D	H01L2924/1776	6	Iron [Fe] as principal constituent	<administrative transfer to H10W 76/17>
D	H01L2924/17763	5	the principal constituent melting at a temperature of greater than 1550 C	<administrative transfer to H10W 76/17>
D	H01L2924/17786	4	with a principal constituent of the material being a non metallic, non metalloid inorganic material	<administrative transfer to H10W 76/17>
D	H01L2924/17787	5	Ceramics, e.g. crystalline carbides, nitrides or oxides	<administrative transfer to H10W 76/17>
D	H01L2924/17788	5	Glasses, e.g. amorphous oxides, nitrides or fluorides	<administrative transfer to H10W 76/17>
D	H01L2924/1779	4	with a principal constituent of the material being a polymer, e.g. polyester, phenolic based polymer, epoxy	<administrative transfer to H10W 76/17>
D	H01L2924/17791	5	The principal constituent being an elastomer, e.g. silicones, isoprene, neoprene	<administrative transfer to H10W 76/17>
D	H01L2924/17793	4	with a principal constituent of the material being a solid not provided for in groups H01L2924/177 - H01L2924/17791, e.g. allotropes of carbon, fullerene, graphite, carbon-nanotubes, diamond	<administrative transfer to H10W 76/17>
D	H01L2924/17798	4	with a principal constituent of the material being a combination of two or more materials in the form of a matrix with a filler, i.e. being a hybrid material, e.g. segmented structures, foams	<administrative transfer to H10W 76/17>
D	H01L2924/181	2	Encapsulation	<administrative transfer to H10W 74/00>
D	H01L2924/1811	3	Structure	<administrative transfer to H10W 74/00>
D	H01L2924/1815	3	Shape	<administrative transfer to H10W 74/10>
D	H01L2924/1816	4	Exposing the passive side of the semiconductor or solid-state body	<administrative transfer to H10W 74/142>
D	H01L2924/18161	5	of a flip chip	<administrative transfer to H10W 74/142>
D	H01L2924/18162	5	of a chip with build-up interconnect	<administrative transfer to H10W 74/142>
D	H01L2924/18165	5	of a wire bonded chip	<administrative transfer to H10W 74/142>
D	H01L2924/182	3	Disposition	<administrative transfer to H10W 74/00>
D	H01L2924/183	3	Connection portion, e.g. seal	<administrative transfer to H10W 74/127>

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D	H01L2924/18301	4	being an anchoring portion, i.e. mechanical interlocking between the encapsulation resin and another package part	<administrative transfer to H10W 74/127>
D	H01L2924/186	3	Material	<administrative transfer to H10W 74/40>
D	H01L2924/19	1	Details of hybrid assemblies other than the semiconductor or other solid state devices to be connected	<no transfer>
D	H01L2924/1901	2	Structure	<no transfer>
D	H01L2924/19011	3	including integrated passive components	<no transfer>
D	H01L2924/19015	3	including thin film passive components	<no transfer>
D	H01L2924/1902	3	including thick film passive components	<no transfer>
D	H01L2924/1903	3	including wave guides	<no transfer>
D	H01L2924/19031	4	being a strip line type	<no transfer>
D	H01L2924/19032	4	being a microstrip line type	<no transfer>
D	H01L2924/19033	4	being a coplanar line type	<no transfer>
D	H01L2924/19038	4	being a hybrid line type	<no transfer>
D	H01L2924/19039	5	impedance transition between different types of wave guides	<no transfer>
D	H01L2924/1904	3	Component type	<no transfer>
D	H01L2924/19041	4	being a capacitor	<no transfer>
D	H01L2924/19042	4	being an inductor	<no transfer>
D	H01L2924/19043	4	being a resistor	<no transfer>
D	H01L2924/1905	2	Shape	<no transfer>
D	H01L2924/19051	3	Impedance matching structure [e.g. balun]	<no transfer>
D	H01L2924/191	2	Disposition	<no transfer>
D	H01L2924/19101	3	of discrete passive components	<no transfer>
D	H01L2924/19102	4	in a stacked assembly with the semiconductor or solid state device	<no transfer>
D	H01L2924/19103	5	interposed between the semiconductor or solid-state device and the die mounting substrate, i.e. chip-on-passive	<no transfer>
D	H01L2924/19104	5	on the semiconductor or solid-state device, i.e. passive-on-chip	<no transfer>
D	H01L2924/19105	4	in a side-by-side arrangement on a common die mounting substrate	<no transfer>
D	H01L2924/19106	4	in a mirrored arrangement on two different side of a common die mounting substrate	<no transfer>
D	H01L2924/19107	4	off-chip wires	<no transfer>
D	H01L2924/20	1	Parameters	<no transfer>
D	H01L2924/201	2	Temperature ranges	<no transfer>
D	H01L2924/20101	3	Temperature range $T < 0\text{ C}$, $T < 273.15\text{ K}$	<no transfer>
D	H01L2924/20102	3	Temperature range $0\text{ C} \leq T < 60\text{ C}$, $273.15\text{ K} \leq T < 333.15\text{ K}$	<no transfer>

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D	H01L2924/20103	3	Temperature range 60 C= $\leq$ T<100 C, 333.15 K= $\leq$ T < 373.15K	<no transfer>
D	H01L2924/20104	3	Temperature range 100 C= $\leq$ T<150 C, 373.15 K= $\leq$ T < 423.15K	<no transfer>
D	H01L2924/20105	3	Temperature range 150 C= $\leq$ T<200 C, 423.15 K= $\leq$ T < 473.15K	<no transfer>
D	H01L2924/20106	3	Temperature range 200 C= $\leq$ T<250 C, 473.15 K= $\leq$ T < 523.15K	<no transfer>
D	H01L2924/20107	3	Temperature range 250 C= $\leq$ T<300 C, 523.15K= $\leq$ T< 573.15K	<no transfer>
D	H01L2924/20108	3	Temperature range 300 C= $\leq$ T<350 C, 573.15K= $\leq$ T< 623.15K	<no transfer>
D	H01L2924/20109	3	Temperature range 350 C= $\leq$ T<400 C, 623.15K= $\leq$ T< 673.15K	<no transfer>
D	H01L2924/2011	3	Temperature range 400 C= $\leq$ T<450 C, 673.15K= $\leq$ T< 723.15K	<no transfer>
D	H01L2924/20111	3	Temperature range 450 C= $\leq$ T<500 C, 723.15K= $\leq$ T< 773.15K	<no transfer>
D	H01L2924/202	2	Electromagnetic wavelength ranges [W]	<no transfer>
D	H01L2924/20201	3	Gamma radiation, i.e. wavelength less than 0.01 nm	<no transfer>
D	H01L2924/20202	3	X-ray radiation, i.e. wavelength 0.01 to 10 nm	<no transfer>
D	H01L2924/2021	3	Ultraviolet radiation	<no transfer>
D	H01L2924/20211	4	UV-C 100= $\leq$ W<280 nm	<no transfer>
D	H01L2924/20212	4	UV-B 280= $\leq$ W<315 nm	<no transfer>
D	H01L2924/20213	4	UV-A 315= $\leq$ W<400 nm	<no transfer>
D	H01L2924/2024	3	Visible spectrum wavelength 390= $\leq$ W<700 nm, i.e. 400-790 THz	<no transfer>
D	H01L2924/2026	3	Infrared radiation 700= $\leq$ W<3000 nm	<no transfer>
D	H01L2924/20261	4	IR-A 700= $\leq$ W<1400 nm, i.e. 215 THz-430 THz	<no transfer>
D	H01L2924/20262	4	IR-B 1400= $\leq$ W<3000 nm, i.e. 100THz-215 THz	<no transfer>
D	H01L2924/20263	4	IR-C 3000 nm= $\leq$ W<1 mm, i.e. 300 GHz-100THz	<no transfer>
D	H01L2924/2027	3	Radio 1 mm - km 300 GHz - 3 Hz	<no transfer>
D	H01L2924/20271	4	Microwave radiation 1 mm - 1 meter, i.e 300 GHz - 300 MHz	<no transfer>
D	H01L2924/203	2	Ultrasonic frequency ranges, i.e. KHz	<no transfer>
D	H01L2924/20301	3	Ultrasonic frequency [f] f<25 kHz	<no transfer>
D	H01L2924/20302	3	Ultrasonic frequency [f] 25 Khz= $\leq$ f< 50 KHz	<no transfer>
D	H01L2924/20303	3	Ultrasonic frequency [f] 50 Khz= $\leq$ f< 75 KHz	<no transfer>
D	H01L2924/20304	3	Ultrasonic frequency [f] 75 Khz= $\leq$ f< 100 KHz	<no transfer>

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D	H01L2924/20305	3	Ultrasonic frequency [f] 100 Khz= $\leq$ f< 125 KHz	<no transfer>
D	H01L2924/20306	3	Ultrasonic frequency [f] 125 Khz= $\leq$ f< 150 KHz	<no transfer>
D	H01L2924/20307	3	Ultrasonic frequency [f] 150 Khz= $\leq$ f< 175 KHz	<no transfer>
D	H01L2924/20308	3	Ultrasonic frequency [f] 175 Khz= $\leq$ f< 200 KHz	<no transfer>
D	H01L2924/20309	3	Ultrasonic frequency [f] f $\geq$ 200 KHz	<no transfer>
D	H01L2924/206	2	Length ranges	<no transfer>
D	H01L2924/2064	3	larger or equal to 1 micron less than 100 microns	<no transfer>
D	H01L2924/20641	3	larger or equal to 100 microns less than 200 microns	<no transfer>
D	H01L2924/20642	3	larger or equal to 200 microns less than 300 microns	<no transfer>
D	H01L2924/20643	3	larger or equal to 300 microns less than 400 microns	<no transfer>
D	H01L2924/20644	3	larger or equal to 400 microns less than 500 microns	<no transfer>
D	H01L2924/20645	3	larger or equal to 500 microns less than 600 microns	<no transfer>
D	H01L2924/20646	3	larger or equal to 600 microns less than 700 microns	<no transfer>
D	H01L2924/20647	3	larger or equal to 700 microns less than 800 microns	<no transfer>
D	H01L2924/20648	3	larger or equal to 800 microns less than 900 microns	<no transfer>
D	H01L2924/20649	3	larger or equal to 900 microns less than 1000 microns	<no transfer>
D	H01L2924/2065	3	larger or equal to 1000 microns less than 1500 microns	<no transfer>
D	H01L2924/20651	3	larger or equal to 1500 microns less than 2000 microns	<no transfer>
D	H01L2924/20652	3	larger or equal to 2000 microns less than 2500 microns	<no transfer>
D	H01L2924/20653	3	larger or equal to 2500 microns less than 3000 microns	<no transfer>
D	H01L2924/20654	3	larger or equal to 3000 microns less than 4000 microns	<no transfer>
D	H01L2924/20655	3	larger or equal to 4000 microns less than 5000 microns	<no transfer>
D	H01L2924/20656	3	larger or equal to 5000 microns less than 6000 microns	<no transfer>
D	H01L2924/20657	3	larger or equal to 6000 microns less than 7000 microns	<no transfer>

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D	H01L2924/20658	3	larger or equal to 7000 microns less than 8000 microns	<no transfer>
D	H01L2924/207	2	Diameter ranges	<no transfer>
D	H01L2924/2075	3	larger or equal to 1 micron less than 10 microns	<no transfer>
D	H01L2924/20751	3	larger or equal to 10 microns less than 20 microns	<no transfer>
D	H01L2924/20752	3	larger or equal to 20 microns less than 30 microns	<no transfer>
D	H01L2924/20753	3	larger or equal to 30 microns less than 40 microns	<no transfer>
D	H01L2924/20754	3	larger or equal to 40 microns less than 50 microns	<no transfer>
D	H01L2924/20755	3	larger or equal to 50 microns less than 60 microns	<no transfer>
D	H01L2924/20756	3	larger or equal to 60 microns less than 70 microns	<no transfer>
D	H01L2924/20757	3	larger or equal to 70 microns less than 80 microns	<no transfer>
D	H01L2924/20758	3	larger or equal to 80 microns less than 90 microns	<no transfer>
D	H01L2924/20759	3	larger or equal to 90 microns less than 100 microns	<no transfer>
D	H01L2924/2076	3	equal to or larger than 100 microns	<no transfer>
D	H01L2924/30	1	Technical effects	<no transfer>
D	H01L2924/301	2	Electrical effects	<no transfer>
D	H01L2924/30101	3	Resistance	<no transfer>
D	H01L2924/30105	3	Capacitance	<no transfer>
D	H01L2924/30107	3	Inductance	<no transfer>
D	H01L2924/3011	3	Impedance	<no transfer>
D	H01L2924/30111	4	matching	<no transfer>
D	H01L2924/302	3	Electrostatic	<no transfer>
D	H01L2924/30201	4	Charge	<no transfer>
D	H01L2924/30205	4	Discharge	<no transfer>
D	H01L2924/3025	3	Electromagnetic shielding	<no transfer>
D	H01L2924/35	2	Mechanical effects	<no transfer>
D	H01L2924/351	3	Thermal stress	<no transfer>
D	H01L2924/3511	4	Warping	<no transfer>
D	H01L2924/3512	4	Cracking	<no transfer>
D	H01L2924/35121	5	Peeling or delaminating	<no transfer>
D	H01L2924/36	2	Material effects	<no transfer>
D	H01L2924/364	3	Polymers	<no transfer>
D	H01L2924/3641	4	Outgassing	<no transfer>

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D	H01L2924/365	3	Metallurgical effects	<no transfer>
D	H01L2924/3651	4	Formation of intermetallics	<administrative transfer to H10W 95/00>
D	H01L2924/36511	5	Purple plague	<administrative transfer to H10W 95/00>
D	H01L2924/3656	4	Formation of Kirkendall voids	<administrative transfer to H10W 95/00>
D	H01L2924/37	2	Effects of the manufacturing process	<no transfer>
D	H01L2924/37001	3	Yield	<no transfer>
D	H01L2924/37002	3	Shelf life	<no transfer>
D	H01L2924/3701	3	increased through put	<no transfer>
D	H01L2924/38	2	Effects and problems related to the device integration	<no transfer>
D	H01L2924/381	3	Pitch distance	<no transfer>
D	H01L2924/384	3	Bump effects	<no transfer>
D	H01L2924/3841	4	Solder bridging	<no transfer>
D	H01L2924/386	3	Wire effects	<no transfer>
D	H01L2924/3861	4	Sag	<no transfer>
D	H01L2924/3862	4	Sweep	<no transfer>
D	H01L2924/40	1	Details of apparatuses used for either manufacturing connectors or connecting the semiconductor or solid-state body	<no transfer>
D	H01L2924/401	2	LASER	<no transfer>
D	H01L2924/40101	3	Mode	<no transfer>
D	H01L2924/40102	4	being pulsed	<no transfer>
D	H01L2924/40103	4	being continuous	<no transfer>
D	H01L2924/40105	3	Beam details	<no transfer>
D	H01L2924/4015	4	Shape	<no transfer>
D	H01L2924/402	3	Type	<no transfer>
D	H01L2924/40201	4	being a chemical	<no transfer>
D	H01L2924/40202	5	Deuterium Fluoride [DF] LASER	<no transfer>
D	H01L2924/40203	5	Hydrogen Fluoride [HF] LASER	<no transfer>
D	H01L2924/40207	5	Dye laser	<no transfer>
D	H01L2924/4025	4	being a gas	<no transfer>
D	H01L2924/40251	5	argon-ion LASER	<no transfer>
D	H01L2924/40252	5	CO2 LASER	<no transfer>
D	H01L2924/40253	5	HeAg LASER	<no transfer>
D	H01L2924/40254	5	HeNe LASER	<no transfer>
D	H01L2924/40255	5	NeCu LASER	<no transfer>
D	H01L2924/403	4	being an Excimer	<no transfer>
D	H01L2924/40301	5	ArF LASER	<no transfer>
D	H01L2924/40302	5	F2 LASER	<no transfer>

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D	H01L2924/40303	5	KrCl LASER	<no transfer>
D	H01L2924/40304	5	KrF LASER	<no transfer>
D	H01L2924/40305	5	XeCl LASER	<no transfer>
D	H01L2924/40306	5	XeF LASER	<no transfer>
D	H01L2924/4035	4	being a fiber hosted LASER	<no transfer>
D	H01L2924/404	4	being a solid state	<no transfer>
D	H01L2924/40401	5	Free electron LASER	<no transfer>
D	H01L2924/40402	5	Photonic crystal LASER	<no transfer>
D	H01L2924/40403	5	Fiber solid state LASER	<no transfer>
D	H01L2924/40404	5	Yttrium Aluminium Garnet Nd:YAG LASER	<no transfer>
D	H01L2924/40405	5	Yttrium Lithium Fluoride Nd:YLF LASER	<no transfer>
D	H01L2924/40406	5	Ruby LASER	<no transfer>
D	H01L2924/40407	5	Yb:YAG LASER	<no transfer>
D	H01L2924/405	3	Wavelength	<no transfer>
D	H01L2924/40501	4	UV spectrum	<no transfer>
D	H01L2924/40502	4	Visible spectrum	<no transfer>
D	H01L2924/40503	4	IR spectrum	<no transfer>

SUBCLASS H10W - GENERIC PACKAGES, INTERCONNECTIONS, CONNECTORS OR OTHER CONSTRUCTIONAL DETAILS OF DEVICES COVERED BY CLASS H10

Type*	Symbol	Indent Level Number of dots (e.g. 0, 1, 2)	Title “CPC only” text should normally be enclosed in {curly brackets}**	Transferred to[#]
N	H10W	Subclass	GENERIC PACKAGES, INTERCONNECTIONS, CONNECTORS OR OTHER CONSTRUCTIONAL DETAILS OF DEVICES COVERED BY CLASS H10	
N	H10W 10/00	0	Isolation regions in semiconductor bodies between components of integrated devices	
N	H10W 10/01	1	{Manufacture or treatment}	
N	H10W 10/011	2	{of isolation regions comprising dielectric materials}	
N	H10W 10/012	3	{using local oxidation of silicon [LOCOS]}	
N	H10W 10/0121	4	{in regions recessed from the surface, e.g. in trenches or grooves}	
N	H10W 10/0123	5	{using auxiliary pillars in the regions}	

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N	H10W 10/0124	5	{the regions having non-rectangular shapes, e.g. rounded (H10W 10/0123 takes precedence)}	
N	H10W 10/0125	4	{comprising introducing electrical impurities in local oxidation regions, e.g. to alter LOCOS oxide growth characteristics}	
N	H10W 10/0126	5	{introducing electrical active impurities in local oxidation regions to create channel stoppers}	
N	H10W 10/0127	6	{using both n-type and p-type impurities, e.g. for isolation of complementary doped regions}	
N	H10W 10/0128	4	{comprising multiple local oxidation process steps}	
N	H10W 10/014	3	{using trench refilling with dielectric materials, e.g. shallow trench isolations}	
N	H10W 10/0142	4	{the dielectric materials being chemical transformed from non-dielectric materials}	
N	H10W 10/0143	4	{comprising concurrently refilling multiple trenches having different shapes or dimensions}	
N	H10W 10/0145	4	{of trenches having shapes other than rectangular or V-shape (H10W 10/0143 takes precedence)}	
N	H10W 10/0147	5	{the shapes being altered by a local oxidation of silicon process, e.g. trench corner rounding by LOCOS}	
N	H10W 10/0148	4	{comprising introducing impurities in side walls or bottom walls of trenches, e.g. for forming channel stoppers}	
N	H10W 10/018	3	{using selective deposition of crystalline silicon, e.g. using epitaxial growth of silicon}	
N	H10W 10/019	3	{using epitaxial passivated integrated circuit [EPIC] processes}	
N	H10W 10/021	2	{of air gaps}	
N	H10W 10/031	2	{of isolation regions comprising PN junctions}	
N	H10W 10/041	2	{of isolation regions comprising polycrystalline semiconductor materials}	
N	H10W 10/051	2	{of isolation region based on field-effect}	
N	H10W 10/061	2	{using SOI processes together with lateral isolation, e.g. combinations of SOI and shallow trench isolations}	
N	H10W 10/10	1	Isolation regions comprising dielectric materials	
N	H10W 10/13	2	formed using local oxidation of silicon [LOCOS], e.g. sealed interface localised	

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			oxidation [SILO] or side-wall mask isolation [SWAMI]	
N	H10W 10/17	2	formed using trench refilling with dielectric materials, e.g. shallow trench isolations	
N	H10W 10/181	2	{Semiconductor-on-insulator [SOI] isolation regions, e.g. buried oxide regions of SOI wafers}	
N	H10W 10/20	1	Air gaps	
N	H10W 10/30	1	Isolation regions comprising PN junctions	
N	H10W 10/40	1	Isolation regions comprising polycrystalline semiconductor materials	
N	H10W 10/50	1	Isolation regions based on field-effect	
N	H10W 15/00	0	Highly-doped buried regions of integrated devices	
N	H10W 15/01	1	{Manufacture or treatment}	
N	H10W 20/00	0	Interconnections in chips, wafers or substrates	
N	H10W 20/01	1	{Manufacture or treatment}	
N	H10W 20/021	2	{of interconnections within wafers or substrates}	
Q	H10W 20/023	3	{the interconnections being through-semiconductor vias}	H10W 20/023, H10W 20/0234, H10W 20/0238, H10W 20/0242, H10W 20/0245, H10W 20/0249, H10W 20/0253, H10W 20/0257, H10W 20/0261, H10W 20/0265
N	H10W 20/0234	4	{comprising etching via holes that stop on pads or on electrodes}	
N	H10W 20/0238	4	{comprising etching via holes through pads or through electrodes}	
N	H10W 20/0242	4	{comprising etching via holes from the back sides of the chips, wafers or substrates}	
N	H10W 20/0245	4	{comprising use of blind vias during the manufacture}	
N	H10W 20/0249	4	{wherein the through-semiconductor via protrudes from backsides of the chips, wafers or substrates during the manufacture}	
N	H10W 20/0253	4	{comprising forming the through-semiconductor vias after stacking of the chips, wafers or substrates}	
N	H10W 20/0257	4	{comprising using a sacrificial placeholder, e.g. using a sacrificial plug}	
N	H10W 20/0261	4	{characterised by the filling method or the material of the conductive fill}	
N	H10W 20/0265	4	{characterised by the sidewall insulation}	
N	H10W 20/031	2	{of conductive parts of the interconnections}	

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N	H10W 20/032	3	{of conductive barrier, adhesion or liner layers}	
N	H10W 20/033	4	{in openings in dielectrics}	
N	H10W 20/034	5	{bottomless barrier, adhesion or liner layers}	
N	H10W 20/035	5	{combinations of barrier, adhesion or liner layers, e.g. multi-layered barrier layers}	
N	H10W 20/036	5	{the barrier, adhesion or liner layers being within a main fill metal}	
Q	H10W 20/037	5	{the barrier, adhesion or liner layers being on top of a main fill metal}	H10W 20/037, H10W 20/0372
N	H10W 20/0372	6	{comprising multiple barrier, adhesion or liner layers}	
N	H10W 20/0375	4	{comprising multiple stacked thin barrier, adhesion or liner layers not being formed in openings in dielectrics}	
N	H10W 20/038	4	{covering conductive structures (H10W 20/037 takes precedence)}	
N	H10W 20/039	5	{also covering sidewalls of the conductive structures}	
N	H10W 20/041	4	{the barrier, adhesion or liner layers being discontinuous}	
N	H10W 20/042	4	{the barrier, adhesion or liner layers being seed or nucleation layers}	
N	H10W 20/0425	5	{comprising multiple stacked seed or nucleation layers}	
N	H10W 20/043	5	{for electroplating}	
N	H10W 20/044	5	{for electroless plating}	
N	H10W 20/045	5	{for deposition from the gaseous phase, e.g. for chemical vapour deposition [CVD]}	
N	H10W 20/046	4	{the barrier, adhesion or liner layers being associated with interconnections of capacitors}	
N	H10W 20/047	4	{by introducing additional elements therein}	
N	H10W 20/048	5	{by using plasmas or gaseous environments, e.g. by nitriding}	
N	H10W 20/049	5	{by diffusing alloying elements}	
N	H10W 20/051	5	{by ion implantation}	
N	H10W 20/052	4	{by treatments not introducing additional elements therein}	
N	H10W 20/0523	5	{by irradiating with ultra violet or particle radiation}	
N	H10W 20/0526	5	{by thermal treatment thereof}	
N	H10W 20/054	4	{by selectively removing parts thereof (H10W 20/034 takes precedence)}	
N	H10W 20/055	4	{by formation methods other than physical vapour deposition [PVD],	

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			chemical vapour deposition [CVD] or liquid deposition}	
N	H10W 20/0552	5	{by diffusing metallic dopants to react with dielectrics}	
N	H10W 20/0554	3	{of nanotubes or nanowires}	
Q	H10W 20/056	3	{by filling conductive material into holes, grooves or trenches}	H10W 20/056, H10W 20/0595
N	H10W 20/057	4	{by selectively depositing, e.g. by using selective CVD or plating}	
N	H10W 20/058	4	{by depositing on sacrificial masks, e.g. using lift-off}	
N	H10W 20/059	4	{by reflowing or applying pressure}	
N	H10W 20/0595	4	{by using multiple deposition steps separated by etching steps}	
N	H10W 20/062	3	{by smoothing of conductive parts, e.g. by planarisation}	
Q	H10W 20/063	3	{by forming conductive members before forming protective insulating material}	H10W 20/063, H10W 20/0633, H10W 20/0636
N	H10W 20/0633	4	{using subtractive patterning of the conductive members}	
N	H10W 20/0636	4	{the conductive members being on sidewalls}	
N	H10W 20/064	3	{by modifying the conductivity of conductive parts, e.g. by alloying}	
N	H10W 20/065	4	{by making at least a portion of the conductive part non-conductive, e.g. by oxidation}	
N	H10W 20/066	4	{by forming silicides of refractory metals}	
N	H10W 20/067	3	{by modifying the pattern of conductive parts}	
N	H10W 20/068	4	{by using a laser, e.g. laser cutting or laser direct writing}	
Q	H10W 20/069	3	{by forming self-aligned vias or self-aligned contact plugs}	H10W 20/069, H10W 20/0693, H10W 20/0696
N	H10W 20/0693	4	{by forming self-aligned vias}	
N	H10W 20/0696	4	{by using sacrificial placeholders, e.g. using sacrificial plugs}	
N	H10W 20/0698	3	{Local interconnections}	
N	H10W 20/071	2	{of dielectric parts thereof}	
N	H10W 20/072	3	{of dielectric parts comprising air gaps}	
N	H10W 20/074	3	{of dielectric parts comprising thin functional dielectric layers, e.g. dielectric etch-stop, barrier, capping or liner layers}	
N	H10W 20/075	4	{of multilayered thin functional dielectric layers}	
N	H10W 20/076	4	{in via holes or trenches}	

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N	H10W 20/0765	5	{the thin functional dielectric layers being temporary, e.g. sacrificial layers}	
N	H10W 20/077	4	{on sidewalls or on top surfaces of conductors (H10W 20/076 takes precedence)}	
N	H10W 20/081	3	{by forming openings in the dielectric parts}	
N	H10W 20/082	4	{the openings being tapered via holes}	
N	H10W 20/083	4	{the openings being via holes penetrating underlying conductors}	
N	H10W 20/084	4	{for dual-damascene structures}	
N	H10W 20/085	5	{involving intermediate temporary filling with material}	
N	H10W 20/086	5	{involving buried masks}	
N	H10W 20/087	5	{involving multiple stacked pre-patterned masks}	
N	H10W 20/088	5	{involving partial etching of via holes}	
N	H10W 20/0882	5	{wherein the dual damascene structure is in a photoresist layer}	
N	H10W 20/0884	5	{involving forming vias by burying sacrificial pillars in the dielectric parts and removing the pillars}	
N	H10W 20/0886	5	{involving forming a via in a via-level dielectric prior to deposition of a trench-level dielectric}	
N	H10W 20/0888	5	{wherein via-level dielectrics are compositionally different than trench-level dielectrics}	
N	H10W 20/089	4	{using processes for implementing desired shapes or dispositions of the openings, e.g. double patterning}	
N	H10W 20/091	4	{by printing or stamping}	
N	H10W 20/092	3	{by smoothing the dielectric parts}	
N	H10W 20/093	3	{by modifying materials of the dielectric parts}	
N	H10W 20/094	4	{by transforming insulators into conductors}	
N	H10W 20/095	4	{by irradiating with electromagnetic or particle radiation (plasma treatment H10W 20/096)}	
N	H10W 20/096	4	{by contacting with gases, liquids or plasmas}	
N	H10W 20/097	4	{by thermally treating}	
N	H10W 20/098	3	{by filling between adjacent conductive parts}	
Q	H10W 20/20	1	Interconnections within wafers or substrates, e.g. through-silicon vias [TSV]	H10W 20/20, H10W 20/211, H10W 20/212, H10W 20/2125, H10W 20/2128, H10W 20/213,

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				H10W 20/2134, H10W 20/215, H10W 20/216, H10W 20/217, H10W 20/218, H10W 20/222, H10W 20/233
N	H10W 20/211	2	{Through-semiconductor vias, e.g. TSVs}	
N	H10W 20/212	3	{Top-view shapes or dispositions, e.g. top-view layouts of the vias}	
N	H10W 20/2125	4	{Top-view shapes}	
N	H10W 20/2128	5	{Coaxial through-semiconductor vias}	
N	H10W 20/213	3	{Cross-sectional shapes or dispositions}	
N	H10W 20/2134	4	{TSVs extending from the semiconductor wafer into back-end-of-line layers}	
N	H10W 20/215	3	{characterised by thin functional layers between the through-semiconductor vias and sidewalls of the via holes, e.g. barrier layers or adhesion layers}	
N	H10W 20/216	3	{characterised by dielectric material at least partially filling the via holes, e.g. covering the through-semiconductor vias in the via holes}	
N	H10W 20/217	3	{comprising ring-shaped isolation structures outside of the via holes}	
N	H10W 20/218	3	{in silicon-on-insulator [SOI] wafers}	
N	H10W 20/222	2	{Vias through non-semiconductor substrates, e.g. through-glass vias}	
N	H10W 20/233	2	{parallel to the active surface, e.g. horizontal traces in trenches in the surface of the wafer}	
Q	H10W 20/40	1	Interconnections external to wafers or substrates, e.g. back-end-of-line [BEOL] metallisations or vias connecting to gate electrodes	H10W 20/40, H10W 20/41, H10W 20/42, H10W 20/421, H10W 20/422, H10W 20/423, H10W 20/425, H10W 20/427, H10W 20/43, H10W 20/432, H10W 20/435, H10W 20/438, H10W 20/44, H10W 20/4403, H10W 20/4405, H10W 20/4407, H10W 20/4421, H10W 20/4424, H10W 20/4432, H10W 20/4435, H10W 20/4441, H10W 20/4446, H10W 20/4451, H10W 20/4462, H10W 20/4473, H10W 20/4484, H10W 20/45, H10W 20/455, H10W 20/46, H10W 20/47, H10W 20/48, H10W

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				20/481, H10W 20/482, H10W 70/60, H10W 70/611, H10W 70/614, H10W 70/616, H10W 70/62, H10W 70/63, H10W 70/635, H10W 70/641, H10W 70/644, H10W 70/65, H10W 70/652, H10W 70/6523, H10W 70/6525, H10W 70/6528, H10W 70/654, H10W 70/655, H10W 70/656, H10W 70/657, H10W 70/658, H10W 70/66, H10W 70/662, H10W 70/664, H10W 70/666, H10W 70/668, H10W 70/67, H10W 70/68, H10W 70/681, H10W 70/682, H10W 70/685, H10W 70/688, H10W 70/69, H10W 70/692, H10W 70/695, H10W 70/698, H10W 72/00
N	H10W 20/41	2	characterised by their conductive parts	
Q	H10W 20/42	3	Vias, e.g. via plugs	H10W 20/42, H10W 20/421, H10W 20/422
N	H10W 20/421	4	{Skip vias, i.e. vias that do not connect all metallization layers that they pass through}	
N	H10W 20/422	4	{Vias connecting to electrodes, e.g. contact plugs}	
N	H10W 20/423	3	{Shielding layers}	
Q	H10W 20/425	3	{Barrier, adhesion or liner layers}	H10W 20/425, H10W 20/455
N	H10W 20/427	3	{Power or ground buses}	
N	H10W 20/43	3	Layouts of interconnections	
N	H10W 20/432	4	{comprising crossing interconnections}	
N	H10W 20/435	3	{Cross-sectional shapes or dispositions of interconnections}	
N	H10W 20/438	3	{Interconnections with multiple fill metals, e.g. having different metals in wide and narrow interconnections, or having different metals in vias and in trenches}	
N	H10W 20/44	3	Conductive materials thereof	
Q	H10W 20/4403	4	{based on metals, e.g. alloys, metal silicides (H10W 20/4484 takes precedence)}	H10W 20/4403, H10W 20/4437
N	H10W 20/4405	5	{the principal metal being a aluminium}	
N	H10W 20/4407	6	{Aluminium alloys}	

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N	H10W 20/4421	5	{the principal metal being copper}	
N	H10W 20/4424	6	{Copper alloys}	
N	H10W 20/4432	5	{the principal metal being a noble metal, e.g. gold}	
N	H10W 20/4435	6	{Noble-metal alloys}	
N	H10W 20/4437	5	{the principal metal being a transition metal}	
N	H10W 20/4441	6	{the principal metal being a refractory metal}	
N	H10W 20/4446	7	{Refractory-metal alloys}	
N	H10W 20/4451	4	{Semiconductor materials, e.g. polysilicon}	
N	H10W 20/4462	4	{Carbon or carbon-containing materials, e.g. graphene}	
N	H10W 20/4473	4	{Conductive organic materials, e.g. conductive adhesives or conductive inks}	
N	H10W 20/4484	4	{Superconducting materials}	
N	H10W 20/45	2	characterised by their insulating parts	
N	H10W 20/455	3	{Thin functional dielectric layers}	
N	H10W 20/46	3	comprising air gaps	
N	H10W 20/47	3	comprising two or more dielectric layers having different properties, e.g. different dielectric constants	
N	H10W 20/48	3	Insulating materials thereof	
N	H10W 20/481	2	{on the rear surfaces of the wafers or substrates}	
N	H10W 20/482	2	{for individual devices provided for in groups H10D 8/00 - H10D 48/00, e.g. for power transistors}	
N	H10W 20/483	3	{Interconnections over air gaps, e.g. air bridges}	
N	H10W 20/484	3	{Interconnections having extended contours, e.g. pads having mesh shape or interconnections comprising connected parallel stripes}	
N	H10W 20/49	2	Adaptable interconnections, e.g. fuses or antifuses	
N	H10W 20/491	3	{Antifuses, i.e. interconnections changeable from non-conductive to conductive}	
N	H10W 20/492	4	{changeable by the use of an external beam, e.g. laser beam or ion beam}	
N	H10W 20/493	3	{Fuses, i.e. interconnections changeable from conductive to non-conductive}	
N	H10W 20/494	4	{changeable by the use of an external beam, e.g. laser beam or ion beam}	
N	H10W 20/495	2	{Capacitive arrangements or effects of, or between wiring layers}	
N	H10W 20/496	3	{Capacitor integral with wiring layers}	

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N	H10W 20/497	2	{Inductive arrangements or effects of, or between, wiring layers}	
N	H10W 20/498	2	{Resistive arrangements or effects of, or between, wiring layers}	
N	H10W 29/00	0	Generic parts of integrated devices, not otherwise provided for	
N	H10W 29/01	1	{Manufacture or treatment}	
Q	H10W 40/00	0	Arrangements for thermal protection or thermal control (integrated devices comprising arrangements for thermal protection H10D89/60)	H10W 40/00, H10W 40/20, H10W 40/50
N	H10W 40/01	1	{Manufacture or treatment}	
N	H10W 40/03	2	{of arrangements for cooling}	
N	H10W 40/033	3	{using mechanical treatments, e.g. deforming, punching or cutting}	
N	H10W 40/037	3	{Assembling together parts thereof}	
N	H10W 40/10	1	Arrangements for heating	
N	H10W 40/20	1	Arrangements for cooling	
Q	H10W 40/22	2	characterised by their shape, e.g. having conical or cylindrical projections	H10W 40/22, H10W 40/226, H10W 40/228, H10W 40/231, H10W 40/233, H10W 40/235, H10W 40/237, H10W 40/242
N	H10W 40/226	3	{characterised by projecting parts, e.g. fins to increase surface area (leadframes for cooling H10W 70/461)}	
N	H10W 40/228	4	{the projecting parts being wire-shaped or pin-shaped}	
N	H10W 40/231	2	{characterised by their places of attachment or cooling paths}	
N	H10W 40/233	3	{attached to chips}	
N	H10W 40/235	3	{attached to package parts}	
N	H10W 40/237	3	{attached to additional arrangements for cooling}	
N	H10W 40/242	3	{comprising thermal conductors between chips and the and the arrangements for cooling, e.g. compliant heat-spreaders}	
N	H10W 40/25	2	characterised by their materials	
N	H10W 40/251	3	{Organics}	
N	H10W 40/253	3	{Semiconductors}	
N	H10W 40/254	3	{Diamond}	
N	H10W 40/255	3	{having a laminate or multilayered structure, e.g. direct bond copper [DBC] ceramic substrates}	

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N	H10W 40/257	3	{having a heterogeneous or anisotropic structure, e.g. powder or fibres in a matrix, wire mesh or porous structures (H10W 40/254, H10W 40/251 take precedence)}	
N	H10W 40/258	3	{Metallic materials (H10W 40/254, H10W 40/257, H10W 40/255, H10W 40/251, H10W 40/253 take precedence)}	
N	H10W 40/259	3	{Ceramics or glasses (H10W 40/254, H10W 40/257, H10W 40/255, H10W 40/251, H10W 40/253 take precedence)}	
N	H10W 40/28	2	comprising Peltier coolers	
N	H10W 40/30	1	wherein the packaged device is completely immersed in a fluid other than air, e.g. immersed in a cryogenic fluid	
N	H10W 40/305	2	{the fluid being a liquefied gas, e.g. liquid nitrogen}	
N	H10W 40/40	1	involving heat exchange by flowing fluids	
N	H10W 40/43	2	by flowing gases, e.g. forced air cooling	
N	H10W 40/47	2	by flowing liquids, e.g. forced water cooling	
N	H10W 40/475	3	{using jet impingement (H10W 40/776 takes precedence)}	
N	H10W 40/50	1	Arrangements for sensing temperature	
N	H10W 40/60	1	Securing means for detachable heating or cooling arrangements, e.g. clamps	
N	H10W 40/611	2	{Bolts or screws}	
N	H10W 40/613	3	{for stacked arrangements of a plurality of semiconductor devices}	
N	H10W 40/625	2	{Clamping parts not primarily conducting heat}	
N	H10W 40/641	2	{Snap-on arrangements, e.g. clips}	
N	H10W 40/70	1	Fillings or auxiliary members in containers or in encapsulations for thermal protection or control	
N	H10W 40/73	2	for cooling by change of state	
N	H10W 40/735	3	{by melting or evaporation of solids}	
N	H10W 40/77	2	Auxiliary members characterised by their shape	
N	H10W 40/772	3	{Bellows}	
N	H10W 40/774	3	{Pistons, e.g. spring-loaded members}	
N	H10W 40/776	3	{Arrangements for jet impingement, e.g. for spraying}	
N	H10W 40/778	3	{in encapsulations}	
N	H10W 40/80	1	Circuit arrangements for thermal protection or control of packages	

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Q	H10W 42/00	0	Arrangements for protection of devices (arrangements for thermal protection H10W 40/00)	H10W 42/00, H10W 42/101, H10W 40/80, H10W 99/00
N	H10W 42/101	1	{protecting against moisture, e.g. getters (fillers in containers for absorbing or reacting with moisture or other undesired substances H10W 76/48)}	
N	H10W 42/121	1	{protecting against mechanical damage (H10W 76/00, H10W 74/00 take precedence)}	
Q	H10W 42/20	1	protecting against electromagnetic or particle radiation, e.g. light, X-rays, gamma-rays or electrons	H10W 42/20, H10W 42/40, H10W 42/261, H10W 42/263, H10W 42/265, H10W 42/267, H10W 42/271, H10W 42/273, H10W 42/276, H10W 42/281, H10W 42/284, H10W 42/287
N	H10W 42/25	2	against alpha rays, e.g. for outer space applications	
N	H10W 42/261	2	{characterised by their shapes or dispositions}	
N	H10W 42/263	3	{Shielding bumps}	
N	H10W 42/265	3	{Shielding wires, e.g. constant potential wires}	
N	H10W 42/267	3	{Patterned shielding planes}	
N	H10W 42/271	3	{the arrangements being between stacked chips}	
N	H10W 42/273	3	{the arrangements being between laterally adjacent chips, e.g. walls between chips}	
N	H10W 42/276	3	{the arrangements being on an external surface of the package, e.g. on the outer surface of an encapsulation}	
N	H10W 42/281	2	{characterised by their materials}	
N	H10W 42/284	3	{shielding resins}	
N	H10W 42/287	3	{materials for magnetic shielding, e.g. ferromagnetic materials}	
N	H10W 42/40	1	protecting against tampering, e.g. unauthorised inspection or reverse engineering	
N	H10W 42/405	2	{using active circuits}	
N	H10W 42/60	1	protecting against electrostatic charges or discharges, e.g. Faraday shields (integrated devices comprising arrangements for electrical protection H10D89/60)	
N	H10W 42/80	1	protecting against overcurrent or overload, e.g. fuses or shunts (integrated devices	

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			comprising arrangements for electrical protection H10D89/60)	
N	H10W 44/00	0	Electrical arrangements for controlling or matching impedance	
N	H10W 44/20	1	at high-frequency [HF] or radio frequency [RF]	
N	H10W 44/203	2	{Electrical connections}	
N	H10W 44/206	3	{Wires}	
N	H10W 44/209	3	{Vertical interconnections, e.g. vias}	
N	H10W 44/212	4	{Coaxial feed-throughs in substrates}	
N	H10W 44/216	3	{Waveguides, e.g. strip lines}	
N	H10W 44/219	4	{characterised by transitions between different types of waveguides}	
N	H10W 44/223	3	{Differential pair signal lines}	
N	H10W 44/226	2	{for HF amplifiers}	
N	H10W 44/231	3	{Arrangements for applying bias}	
N	H10W 44/234	3	{Arrangements for impedance matching}	
N	H10W 44/241	2	{for passive devices or passive elements}	
N	H10W 44/243	3	{for decoupling, e.g. bypass capacitors}	
N	H10W 44/248	3	{for antennas}	
N	H10W 44/251	2	{for monolithic microwave integrated circuits [MMIC]}	
N	H10W 44/255	2	{for operation at multiple different frequencies}	
N	H10W 44/259	2	{Optical signal interface}	
N	H10W 44/401	1	{Resistive arrangements (H10W 44/20, H10W 42/80 take precedence)}	
N	H10W 44/501	1	{Inductive arrangements (H10W 44/20 takes precedence)}	
N	H10W 44/601	1	{Capacitive arrangements (H10W 44/20 takes precedence)}	
N	H10W 46/00	0	Marks applied to devices, e.g. for alignment or identification	
N	H10W 46/101	1	{characterised by the type of information, e.g. logos or symbols}	
N	H10W 46/103	2	{alphanumeric information, e.g. words, letters or serial numbers}	
N	H10W 46/106	2	{digital information, e.g. bar codes}	
N	H10W 46/201	1	{located on the periphery of wafers, e.g. orientation notches or lot numbers}	
N	H10W 46/301	1	{for alignment}	
N	H10W 46/401	1	{for identification or tracking}	
N	H10W 46/403	2	{for non-wireless electrical read out}	
N	H10W 46/407	2	{for wireless electrical read out}	

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N	H10W 46/501	1	{for use before dicing}	
N	H10W 46/503	2	{Located in scribe lines}	
N	H10W 46/507	2	{Located in dummy chips or in reference chips}	
N	H10W 46/601	1	{for use after dicing}	
N	H10W 46/603	2	{Formed on wafers or substrates before dicing and remaining on chips after dicing}	
N	H10W 46/607	2	{Located on parts of packages, e.g. on encapsulations or on package substrates}	
N	H10W 70/00	0	Package substrates; Interposers; Redistribution layers [RDL]	
N	H10W 70/01	1	Manufacture or treatment	
Q	H10W 70/02	2	of conductive package substrates serving as an interconnection, e.g. of metal plates (manufacture or treatment of leadframes H10W 70/04)	H10W 70/02, H10W 40/03
N	H10W 70/023	3	{Connecting or disconnecting interconnections thereto or therefrom, e.g. connecting bond wires or bumps}	
Q	H10W 70/027	3	{Mechanical treatments, e.g. deforming, punching or cutting}	H10W 40/033, H10W 70/027
N	H10W 70/04	2	of leadframes	
N	H10W 70/041	3	{Connecting or disconnecting interconnections to or from leadframes, e.g. connecting bond wires or bumps}	
N	H10W 70/042	3	{Etching}	
N	H10W 70/045	3	{Cleaning}	
N	H10W 70/047	3	{Attaching leadframes to insulating supports, e.g. for tape automated bonding [TAB]}	
N	H10W 70/048	3	{Mechanical treatments, e.g. punching, cutting, deforming or cold welding}	
Q	H10W 70/05	2	of insulating or insulated package substrates, or of interposers, or of redistribution layers (manufacture or treatment of leadframes H10W 70/04)	H10W 70/05, H10W 70/06, H10W 70/08, H10W 70/09, H10W 70/092, H10W 70/093, H10W 70/095, H10W 70/096, H10W 70/097, H10W 70/098
N	H10W 70/06	3	using temporary auxiliary supports	
N	H10W 70/08	3	by depositing layers on the chip or wafer, e.g. "chip-first" RDLs	
N	H10W 70/09	4	extending onto an encapsulation that laterally surrounds the chip or wafer, e.g. fan-out wafer level package [FOWLP] RDLs	
N	H10W 70/092	3	{Adapting interconnections, e.g. making engineering charges, repairing}	

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N	H10W 70/093	3	{Connecting or disconnecting other interconnections thereto or therefrom, e.g. connecting bond wires or bumps}	
N	H10W 70/095	3	{of vias therein}	
N	H10W 70/096	3	{Cutting or separating}	
N	H10W 70/097	3	{Cleaning}	
N	H10W 70/098	3	{Applying pastes or inks, e.g. screen printing (H10W 70/095 takes precedence)}	
N	H10W 70/099	1	{Connecting interconnections to insulating or insulated package substrates, interposers or redistribution layers}	
N	H10W 70/20	1	Conductive package substrates serving as an interconnection, e.g. metal plates (leadframes H10W 70/40)	
N	H10W 70/22	2	{having an heterogeneous or anisotropic structure}	
N	H10W 70/24	2	{characterised by materials}	
N	H10W 70/26	3	{Semiconductor materials}	
N	H10W 70/28	3	{Carbon-containing materials}	
N	H10W 70/40	1	Leadframes	
N	H10W 70/411	2	{Chip-supporting parts, e.g. die pads}	
N	H10W 70/413	3	{Insulating or insulated substrates serving as die pads (H10W 70/468 takes precedence)}	
N	H10W 70/415	3	{Leadframe inner leads serving as die pads}	
N	H10W 70/417	3	{Bonding materials between chips and die pads}	
N	H10W 70/421	2	{Shapes or dispositions}	
N	H10W 70/424	3	{Cross-sectional shapes (H10W 70/481 takes precedence)}	
N	H10W 70/427	4	{Bent parts}	
N	H10W 70/429	5	{being the outer leads}	
N	H10W 70/433	3	{of deformation-absorbing parts, e.g. leads having meandering shapes (H10W 70/481 takes precedence)}	
N	H10W 70/435	3	{of insulating layers on leadframes, e.g. bridging members}	
N	H10W 70/438	3	{of side rails, e.g. having holes}	
N	H10W 70/442	3	{of multiple leadframes in a single chip}	
N	H10W 70/451	2	{Multilayered leadframes}	
N	H10W 70/453	2	{comprising flexible metallic tapes}	
N	H10W 70/456	2	{Materials}	
N	H10W 70/457	3	{of metallic layers on leadframes}	
N	H10W 70/458	3	{of insulating layers on leadframes}	
N	H10W 70/461	2	{specially adapted for cooling}	

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N	H10W 70/464	2	{Additional interconnections in combination with leadframes}	
N	H10W 70/465	3	{Bumps or wires}	
N	H10W 70/466	3	{Tape carriers or flat leads}	
N	H10W 70/467	3	{Multilayered additional interconnections}	
N	H10W 70/468	3	{Circuit boards}	
N	H10W 70/474	2	{Batteries in combination with leadframes}	
N	H10W 70/475	2	{Capacitors in combination with leadframes}	
N	H10W 70/476	2	{Oscillators in combination with leadframes}	
N	H10W 70/479	2	{on or in insulating or insulated package substrates, interposers, or redistribution layers}	
N	H10W 70/481	2	{for devices being provided for in groups H10D 8/00 - H10D 48/00}	
Q	H10W 70/60	1	Insulating or insulated package substrates; Interposers; Redistribution layers (leadframes H10W 70/40)	H10W 70/60, H10W 70/611, H10W 70/614, H10W 70/616, H10W 70/618, H10W 70/62, H10W 70/63, H10W 70/635, H10W 70/641, H10W 70/644, H10W 70/65, H10W 70/652, H10W 70/6523, H10W 70/6525, H10W 70/6528, H10W 70/654, H10W 70/655, H10W 70/656, H10W 70/6565, H10W 70/657, H10W 70/658, H10W 70/66, H10W 70/662, H10W 70/664, H10W 70/666, H10W 70/668, H10W 70/67, H10W 70/68, H10W 70/681, H10W 70/682, H10W 70/685, H10W 70/686, H10W 70/687, H10W 70/69, H10W 70/692, H10W 70/695, H10W 70/698, H10W 70/699
N	H10W 70/611	2	{for connecting multiple chips together}	
N	H10W 70/614	3	{the multiple chips being integrally enclosed}	
N	H10W 70/616	3	{package substrates, interposers or redistribution layers combined with bridge chips}	
N	H10W 70/618	4	{the bridge chips being embedded in the package substrates, interposers or redistribution layers}	

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N	H10W 70/62	2	characterised by their interconnections	
N	H10W 70/63	3	Vias, e.g. via plugs	
N	H10W 70/635	4	{Through-vias}	
N	H10W 70/641	3	{Adaptable interconnections, e.g. fuses or antifuses}	
N	H10W 70/644	3	{Elastic or compliant interconnections, e.g. springs, cantilevers or elastic pads}	
Q	H10W 70/65	3	Shapes or dispositions of interconnections	H10W 70/65, H10W 70/652, H10W 70/6523, H10W 70/6525, H10W 70/6528, H10W 70/654, H10W 70/655, H10W 70/656, H10W 70/6565, H10W 70/657, H10W 70/658
N	H10W 70/652	4	Cross-sectional shapes	
N	H10W 70/6523	5	{for connecting to pads at different heights at the same side of the package substrate, interposer or RDL}	
N	H10W 70/6525	5	{for securing the interconnections to the substrate, e.g. to prevent peeling}	
N	H10W 70/6528	5	{of the portions that connect to chips, wafers or package parts}	
N	H10W 70/654	4	Top-view layouts	
N	H10W 70/655	5	Fan-out layouts	
N	H10W 70/656	5	Fan-in layouts	
N	H10W 70/6565	4	{recessed into the surface of the package substrates, interposers, or redistribution layers}	
N	H10W 70/657	4	{on sidewalls or bottom surfaces of the package substrates, interposers or redistribution layers}	
N	H10W 70/658	4	{for devices provided for in groups H10D 8/00 - H10D 48/00}	
Q	H10W 70/66	3	Conductive materials thereof	H10W 70/66, H10W 70/662, H10W 70/664, H10W 70/666, H10W 70/668
N	H10W 70/662	4	{Semiconductor materials}	
N	H10W 70/664	4	{Carbon-based materials, e.g. fullerenes}	
N	H10W 70/666	4	{Organic materials or pastes}	
N	H10W 70/668	4	{Superconducting materials}	
N	H10W 70/67	2	characterised by their insulating layers or insulating parts	
N	H10W 70/68	3	Shapes or dispositions thereof	

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N	H10W 70/681	4	{comprising holes not having chips therein, e.g. for outgassing, underfilling or bond wire passage}	
N	H10W 70/682	4	{comprising holes having chips therein}	
Q	H10W 70/685	4	comprising multiple insulating layers	H10W 70/685, H10W 70/686, H10W 70/687
N	H10W 70/686	5	{the multiple insulating layers having different compositions, e.g. polymer layer on glass substrate}	
N	H10W 70/687	5	{characterized by the outer layers being for protection, e.g. solder masks, or for protection against chemical or mechanical damage}	
N	H10W 70/6875	4	{being on a metallic substrate, e.g. insulated metal substrates [IMS]}	
N	H10W 70/688	3	{Flexible insulating substrates}	
Q	H10W 70/69	3	Insulating materials thereof	H10W 70/69, H10W 70/692, H10W 70/695, H10W 70/698, H10W 70/686
N	H10W 70/692	4	Ceramics or glasses	
N	H10W 70/695	4	Organic materials	
N	H10W 70/698	4	Semiconductor materials that are electrically insulating, e.g. undoped silicon	
N	H10W 70/699	2	{for flat cards, e.g. credit cards}	
Q	H10W 72/00	0	Interconnections or connectors in packages	H10W 72/00, H10W 72/20, H10W 72/221, H10W 72/222, H10W 72/223, H10W 72/224, H10W 72/225, H10W 72/227, H10W 72/228, H10W 72/231, H10W 72/232, H10W 72/234, H10W 72/235, H10W 72/237, H10W 72/241, H10W 72/242, H10W 72/244, H10W 72/245, H10W 72/247, H10W 72/248, H10W 72/251, H10W 72/252, H10W 72/253, H10W 72/255, H10W 72/257, H10W 72/2524, H10W 72/2528, H10W 72/261, H10W 72/263, H10W 72/265, H10W 72/267, H10W 72/281, H10W 72/283, H10W 72/285, H10W 72/287, H10W 72/30, H10W 72/321, H10W

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				72/322, H10W 72/323, H10W 72/324, H10W 72/325 H10W 72/327, H10W 72/328, H10W 72/331, H10W 72/332, H10W 72/334, H10W 72/335, H10W 72/337, H10W 72/341, H10W 72/342, H10W 72/344, H10W 72/345, H10W 72/347, H10W 72/348, H10W 72/351, H10W 72/352, H10W 72/353, H10W 72/354, H10W 72/355, H10W 72/357, H10W 72/3524, H10W 72/3528, H10W 72/361, H10W 72/365, H10W 72/367, H10W 72/381, H10W 72/383, H10W 72/385, H10W 72/387, H10W 72/40, H10W 72/49, H10W 72/50, H10W 72/521, H10W 72/522, H10W 72/523, H10W 72/524, H10W 72/525, H10W 72/527, H10W 72/528, H10W 72/531, H10W 72/533, H10W 72/534, H10W 72/535, H10W 72/537, H10W 72/536, H10W 72/5363, H10W 72/5366, H10W 72/5368, H10W 72/541, H10W 72/543, H10W 72/547, H10W 72/5434, H10W 72/5438, H10W 72/5473, H10W 72/5475, H10W 72/5445, H10W 72/5449, H10W 72/5453, H10W 72/551, H10W 72/552, H10W 72/5522, H10W 72/5524, H10W 72/5525, H10W 72/553, H10W 72/555, H10W 72/557, H10W 72/5528, H10W 72/581, H10W 72/583, H10W 72/585, H10W 72/60, H10W 72/621, H10W 72/622, H10W 72/623, H10W 72/624, H10W 72/625, H10W 72/627,

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				H10W 72/631, H10W 72/634, H10W 72/635, H10W 72/637, H10W 72/641, H10W 72/645, H10W 72/647, H10W 72/646, H10W 72/642, H10W 72/643, H10W 72/6478, H10W 72/651, H10W 72/652, H10W 72/653, H10W 72/6528, H10W 72/655, H10W 72/657, H10W 72/681, H10W 72/683, H10W 72/685, H10W 72/691
Q	H10W 72/01	1	{Manufacture or treatment}	H10W 72/01, H10W 72/011, H10W 72/0112, H10W 72/0113, H10W 72/0115, H10W 72/0116, H10W 72/012, H10W 72/01204, H10W 72/01208, H10W 72/01212, H10W 72/01215, H10W 72/01221, H10W 72/01223, H10W 72/01225, H10W 72/01231, H10W 72/01233, H10W 72/01235, H10W 72/01236, H10W 72/01238, H10W 72/01251, H10W 72/01253, H10W 72/01255, H10W 72/01257, H10W 72/01261, H10W 72/01265, H10W 72/01271, H10W 72/013, H10W 72/01304, H10W 72/01308, H10W 72/01315, H10W 72/01321, H10W 72/01323, H10W 72/01325, H10W 72/01331, H10W 72/01333, H10W 72/01335, H10W 72/01336, H10W 72/01338, H10W 72/01351, H10W 72/01353, H10W 72/01355, H10W 72/01357, H10W

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				72/01359, H10W 72/01361, H10W 72/01365, H10W 72/01371, H10W 72/014, H10W 72/015, H10W 72/01504, H10W 72/01515, H10W 72/01551, H10W 72/01553, H10W 72/01561, H10W 72/01565, H10W 72/01571, H10W 72/016, H10W 72/01604, H10W 72/01615, H10W 72/01651, H10W 72/01653, H10W 72/01661, H10W 72/01665, H10W 72/01671, H10W 72/019, H10W 72/01904, H10W 72/01908, H10W 72/01921, H10W 72/01923, H10W 72/01925, H10W 72/01931, H10W 72/01933, H10W 72/01935, H10W 72/01936, H10W 72/01938, H10W 72/01951, H10W 72/01953, H10W 72/01955, H10W 72/01961, H10W 72/01971, H10W 72/0198
N	H10W 72/011	2	{Apparatus therefor}	
N	H10W 72/0112	3	{Apparatus for manufacturing bump connectors}	
N	H10W 72/0113	3	{Apparatus for manufacturing die-attach connectors}	
N	H10W 72/0115	3	{Apparatus for manufacturing bond wires}	
N	H10W 72/0116	3	{Apparatus for manufacturing strap connectors}	
Q	H10W 72/012	2	{of bump connectors, dummy bumps or thermal bumps}	H10W 72/012, H10W 72/01204, H10W 72/01208, H10W 72/01212, H10W 72/01215, H10W 72/01221, H10W 72/01223, H10W

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				72/01225, H10W 72/01231, H10W 72/01233, H10W 72/01235, H10W 72/01236, H10W 72/01238, H10W 72/01251, H10W 72/01253, H10W 72/01255, H10W 72/01257, H10W 72/01261, H10W 72/01265, H10W 72/01271
N	H10W 72/01204	3	{using temporary auxiliary members, e.g. using sacrificial coatings or handle substrates}	
N	H10W 72/01208	3	{using permanent auxiliary members, e.g. using solder flow barriers, spacers or alignment marks}	
N	H10W 72/01212	3	{at a different location than on the final device, e.g. forming as prepreg}	
N	H10W 72/01215	3	{forming coatings}	
N	H10W 72/01221	3	{using local deposition}	
N	H10W 72/01223	4	{in liquid form, e.g. by dispensing droplets or by screen printing}	
N	H10W 72/01225	4	{in solid form, e.g. by using a powder or by stud bumping}	
N	H10W 72/01231	3	{using blanket deposition}	
N	H10W 72/01233	4	{in liquid form, e.g. spin coating, spray coating or immersion coating}	
N	H10W 72/01235	5	{by plating, e.g. electroless plating or electroplating}	
N	H10W 72/01236	4	{in solid form, e.g. by using a powder or by laminating a foil}	
N	H10W 72/01238	4	{in gaseous form, e.g. by CVD or PVD}	
N	H10W 72/01251	3	{Changing the shapes of bumps}	
N	H10W 72/01253	4	{by etching}	
N	H10W 72/01255	4	{by using masks}	
N	H10W 72/01257	4	{by reflowing}	
N	H10W 72/01261	3	{Chemical or physical modification, e.g. by sintering or anodisation (patterning H10W 72/01251)}	
N	H10W 72/01265	3	{Thermally treating (reflowing H10W 72/01257)}	
N	H10W 72/01271	3	{Cleaning, e.g. oxide removal or de-smearing}	

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Q	H10W 72/013	2	{of die-attach connectors}	H10W 72/013, H10W 72/01304, H10W 72/01308, H10W 72/01315, H10W 72/01321, H10W 72/01323, H10W 72/01325, H10W 72/01331, H10W 72/01333, H10W 72/01335, H10W 72/01336, H10W 72/01338, H10W 72/01351, H10W 72/01353, H10W 72/01355, H10W 72/01357, H10W 72/01359, H10W 72/01361, H10W 72/01365, H10W 72/01371
N	H10W 72/01304	3	{using temporary auxiliary members, e.g. using sacrificial coatings or handle substrates}	
N	H10W 72/01308	3	{using permanent auxiliary members, e.g. using alignment marks}	
N	H10W 72/01315	3	{Forming coatings}	
N	H10W 72/01321	3	{using local deposition}	
N	H10W 72/01323	4	{in liquid form, e.g. by dispensing droplets or by screen printing}	
N	H10W 72/01325	4	{in solid form}	
N	H10W 72/01331	3	{using blanket deposition}	
N	H10W 72/01333	4	{in liquid form, e.g. spin coating, spray coating or immersion coating}	
N	H10W 72/01335	5	{by plating, e.g. electroless plating or electroplating}	
N	H10W 72/01336	4	{in solid form, e.g. by using a powder or by laminating a foil}	
N	H10W 72/01338	4	{in gaseous form, e.g. by CVD or PVD}	
N	H10W 72/01351	3	{Changing the shapes of die-attach connectors}	
N	H10W 72/01353	4	{by etching}	
N	H10W 72/01355	4	{by use of masks}	
N	H10W 72/01357	4	{by reflowing or heating}	
N	H10W 72/01359	4	{by planarisation, e.g. chemical-mechanical polishing [CMP]}	

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N	H10W 72/01361	3	{Chemical or physical modification, e.g. by sintering or anodisation (patterning H10W 72/01351)}	
N	H10W 72/01365	3	{Thermally treating (reflowing H10W 72/01357)}	
N	H10W 72/01371	3	{Cleaning, e.g. oxide removal or de-smearing}	
N	H10W 72/014	2	{of anisotropic conductive adhesives}	
Q	H10W 72/015	2	{of bond wires}	H10W 72/015, H10W 72/01504, H10W 72/01515, H10W 72/01551, H10W 72/01553, H10W 72/01561, H10W 72/01565, H10W 72/01571
N	H10W 72/01504	3	{using temporary auxiliary members, e.g. using sacrificial coatings or handle substrates}	
N	H10W 72/01515	3	{Forming coatings}	
N	H10W 72/01551	3	{Changing the shapes of bond wires}	
N	H10W 72/01553	4	{by etching}	
N	H10W 72/01561	3	{Chemical or physical modification, e.g. by sintering or anodisation (patterning H10W 72/01551)}	
N	H10W 72/01565	3	{Thermally treating}	
N	H10W 72/01571	3	{Cleaning, e.g. oxide removal or de-smearing}	
Q	H10W 72/016	2	{of strap connectors}	H10W 72/016, H10W 72/01604, H10W 72/01615, H10W 72/01651, H10W 72/01653, H10W 72/01661, H10W 72/01665, H10W 72/01671
N	H10W 72/01604	3	{using temporary auxiliary members, e.g. using sacrificial coatings or handle substrates}	
N	H10W 72/01615	3	{Forming coatings}	
N	H10W 72/01651	3	{Changing the shapes of strap connectors}	
N	H10W 72/01653	4	{by etching}	
N	H10W 72/01661	3	{Chemical or physical modification, e.g. by sintering or anodisation (patterning H10W 72/01651)}	
N	H10W 72/01665	3	{Thermally treating}	
N	H10W 72/01671	3	{Cleaning, e.g. oxide removal or de-smearing}	

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Q	H10W 72/019	2	{of bond pads}	H10W 72/019, H10W 72/01904, H10W 72/01908, H10W 72/01921, H10W 72/01923, H10W 72/01925, H10W 72/01931, H10W 72/01933, H10W 72/01935, H10W 72/01936, H10W 72/01938, H10W 72/01951, H10W 72/01953, H10W 72/01955, H10W 72/01961, H10W 72/01971
N	H10W 72/01904	3	{using temporary auxiliary members, e.g. using sacrificial coatings or handle substrates}	
N	H10W 72/01908	3	{using permanent auxiliary members, e.g. using alignment marks}	
N	H10W 72/01921	3	{using local deposition}	
N	H10W 72/01923	4	{in liquid form, e.g. by dispensing droplets or by screen printing}	
N	H10W 72/01925	4	{in solid form}	
N	H10W 72/01931	3	{using blanket deposition}	
N	H10W 72/01933	4	{in liquid form, e.g. spin coating, spray coating or immersion coating}	
N	H10W 72/01935	5	{by plating, e.g. electroless plating or electroplating}	
N	H10W 72/01936	4	{in solid form, e.g. by using a powder or by laminating a foil}	
N	H10W 72/01938	4	{in gaseous form, e.g. by CVD or PVD}	
N	H10W 72/01951	3	{Changing the shapes of bond pads}	
N	H10W 72/01953	4	{by etching}	
N	H10W 72/01955	4	{by using masks}	
N	H10W 72/01961	3	{Chemical or physical modification, e.g. by sintering or anodisation (patterning H10W 72/01951)}	
N	H10W 72/01971	3	{Cleaning, e.g. oxide removal}	
N	H10W 72/0198	2	{batch processes}	
N	H10W 72/071	1	{Connecting or disconnecting}	
N	H10W 72/0711	2	{Apparatus therefor}	
N	H10W 72/07113	3	{Means for calibration}	
N	H10W 72/07118	3	{Means for cleaning, e.g. brushes}	
N	H10W 72/07125	3	{Means for controlling the bonding environment, e.g. valves or vacuum pumps}	

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N	H10W 72/07131	3	{Means for applying material, e.g. for deposition or forming coatings}	
N	H10W 72/07139	3	{Means for protection against electrical discharge}	
N	H10W 72/07141	3	{Means for applying energy, e.g. ovens or lasers}	
N	H10W 72/07152	3	{Means for cooling}	
N	H10W 72/07163	3	{Means for mechanical processing, e.g. for planarising, pressing, stamping or drilling}	
N	H10W 72/07168	3	{Means for storing or moving the material for the connector}	
N	H10W 72/07173	3	{Means for moving chips, wafers or other parts, e.g. conveyor belts}	
N	H10W 72/07178	3	{Means for aligning}	
N	H10W 72/07183	3	{Means for monitoring}	
N	H10W 72/07188	3	{Apparatus chuck}	
N	H10W 72/072	2	{of bump connectors}	
N	H10W 72/07202	3	{using auxiliary members}	
Q	H10W 72/07204	4	{using temporary auxiliary members, e.g. sacrificial coatings}	H10W 72/07204, H10W 72/07207
N	H10W 72/07207	5	{Temporary substrates, e.g. removable substrates}	
N	H10W 72/07211	3	{Treating the bond pad before connecting, e.g. by applying flux or cleaning}	
N	H10W 72/07221	3	{Aligning}	
N	H10W 72/07223	4	{Active alignment, e.g. using optical alignment using marks or sensors}	
N	H10W 72/07227	4	{involving guiding structures, e.g. spacers or supporting members}	
N	H10W 72/07231	3	{Techniques}	
Q	H10W 72/07232	4	{Compression bonding, e.g. thermocompression bonding}	H10W 72/00, H10W 72/07232, H10W 72/07332, H10W 72/07532, H10W 72/07632, H10W 95/00
Q	H10W 72/07233	5	{Ultrasonic bonding, e.g. thermosonic bonding}	H10W 72/00, H10W 72/07233, H10W 72/07333, H10W 72/07533, H10W 72/07633, H10W 95/00
N	H10W 72/07234	4	{Using a reflow oven}	
N	H10W 72/07235	4	{Applying EM radiation, e.g. induction heating or using a laser}	
Q	H10W 72/07236	4	{Soldering or alloying}	H10W 72/00, H10W 72/07236, H10W 72/07336, H10W

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				72/07536, H10W 72/07636, H10W 95/00
N	H10W 72/07237	4	{using a polymer adhesive, e.g. an adhesive based on silicone or epoxy}	
N	H10W 72/07241	3	{Controlling the environment, e.g. atmosphere composition or temperature}	
N	H10W 72/07251	3	{characterised by changes in properties of the bump connectors during connecting}	
N	H10W 72/07252	4	{changes in structures or sizes}	
N	H10W 72/07253	4	{changes in shapes}	
N	H10W 72/07254	4	{changes in dispositions}	
N	H10W 72/07255	4	{changes in materials}	
N	H10W 72/07261	3	{with the bump connectors facing upwards, i.e. not in flip-chip orientation}	
N	H10W 72/073	2	{of die-attach connectors}	
N	H10W 72/07302	3	{using an auxiliary member}	
N	H10W 72/07304	4	{the auxiliary member being temporary, e.g. a sacrificial coating}	
N	H10W 72/07307	5	{the auxiliary member being a temporary substrate, e.g. a removable substrate}	
N	H10W 72/07311	3	{Treating the bonding area before connecting, e.g. by applying flux or cleaning}	
N	H10W 72/07321	3	{Aligning}	
N	H10W 72/07323	4	{Active alignment, e.g. using optical alignment using marks or sensors}	
N	H10W 72/07327	4	{involving guiding structures, e.g. spacers or supporting members}	
N	H10W 72/07331	3	{Connecting techniques}	
N	H10W 72/07332	4	{Compression bonding, e.g. thermocompression bonding}	
N	H10W 72/07333	5	{Ultrasonic bonding, e.g. thermosonic bonding}	
N	H10W 72/07334	4	{Using a reflow oven}	
N	H10W 72/07335	4	{Applying EM radiation, e.g. induction heating or using a laser}	
N	H10W 72/07336	4	{Soldering or alloying}	
N	H10W 72/07337	4	{using a polymer adhesive, e.g. an adhesive based on silicone or epoxy}	
N	H10W 72/07338	5	{hardening the adhesive by curing, e.g. thermosetting}	
N	H10W 72/07339	5	{hardening the adhesive by cooling, e.g. thermoplastics}	
N	H10W 72/07341	3	{Controlling the bonding environment, e.g. atmosphere composition or temperature}	
N	H10W 72/07351	3	{characterised by changes in properties of the die-attach connectors during connecting}	

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N	H10W 72/07352	4	{changes in structures or sizes}	
N	H10W 72/07353	4	{changes in shapes}	
N	H10W 72/07354	4	{changes in dispositions}	
N	H10W 72/07355	4	{changes in materials}	
N	H10W 72/074	2	{of anisotropic conductive adhesives}	
N	H10W 72/075	2	{of bond wires}	
N	H10W 72/07502	3	{using an auxiliary member}	
N	H10W 72/07504	4	{the auxiliary member being temporary, e.g. a sacrificial coating}	
N	H10W 72/07507	5	{the auxiliary member being a temporary substrate, e.g. a removable substrate}	
N	H10W 72/07511	3	{Treating the bonding area before connecting, e.g. by applying flux or cleaning}	
N	H10W 72/07521	3	{Aligning}	
N	H10W 72/07523	4	{Active alignment, e.g. using optical alignment using marks or sensors}	
N	H10W 72/07527	4	{involving guiding structures, e.g. spacers or supporting members}	
N	H10W 72/07531	3	{Techniques}	
N	H10W 72/07532	4	{Compression bonding, e.g. thermocompression bonding}	
N	H10W 72/07533	5	{Ultrasonic bonding, e.g. thermosonic bonding}	
N	H10W 72/07535	4	{Applying EM radiation, e.g. induction heating or using a laser}	
N	H10W 72/07536	4	{Soldering or alloying}	
N	H10W 72/07537	4	{using a polymer adhesive, e.g. an adhesive based on silicone or epoxy}	
N	H10W 72/07541	3	{Controlling the environment, e.g. atmosphere composition or temperature}	
N	H10W 72/07551	4	{characterised by changes in properties of the bond wires during the connecting}	
N	H10W 72/07552	4	{changes in structures or sizes}	
N	H10W 72/07553	4	{changes in shapes}	
N	H10W 72/07554	4	{changes in dispositions}	
N	H10W 72/07555	4	{changes in materials}	
N	H10W 72/076	2	{of strap connectors}	
N	H10W 72/07602	3	{using an auxiliary member}	
N	H10W 72/07604	4	{the auxiliary member being temporary, e.g. a sacrificial coating}	
N	H10W 72/07607	5	{the auxiliary member being a temporary substrate, e.g. a removable substrate}	
N	H10W 72/07611	3	{Treating the bonding area before connecting, e.g. by applying flux or cleaning}	

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N	H10W 72/07621	3	{Aligning}	
N	H10W 72/07623	4	{Active alignment, e.g. using optical alignment using marks or sensors}	
N	H10W 72/07627	4	{involving guiding structures, e.g. spacers or supporting members}	
N	H10W 72/07631	3	{Techniques}	
N	H10W 72/07632	4	{Compression bonding, e.g. thermocompression bonding}	
N	H10W 72/07633	5	{Ultrasonic bonding, e.g. thermosonic bonding}	
N	H10W 72/07635	4	{Applying EM radiation, e.g. induction heating or using a laser}	
N	H10W 72/07636	4	{Soldering or alloying}	
N	H10W 72/07637	4	{using a polymer adhesive, e.g. an adhesive based on silicone or epoxy}	
N	H10W 72/07641	3	{Controlling the environment, e.g. atmosphere composition or temperature}	
N	H10W 72/07651	3	{characterised by changes in properties of the strap connectors during connecting}	
N	H10W 72/07652	4	{changes in structures or sizes}	
N	H10W 72/07653	4	{changes in shapes}	
N	H10W 72/07654	4	{changes in dispositions}	
N	H10W 72/07655	4	{changes in materials}	
N	H10W 72/077	2	{Connecting of TAB connectors}	
Q	H10W 72/20	1	Bump connectors, e.g. solder bumps or copper pillars; Dummy bumps; Thermal bumps	H10W 72/20, H10W 72/221, H10W 72/222, H10W 72/223, H10W 72/224, H10W 72/225, H10W 72/227, H10W 72/228, H10W 72/231, H10W 72/232, H10W 72/234, H10W 72/235, H10W 72/237, H10W 72/241, H10W 72/242, H10W 72/244, H10W 72/245, H10W 72/247, H10W 72/248, H10W 72/251, H10W 72/252, H10W 72/253, H10W 72/255, H10W 72/257, H10W 72/2524, H10W 72/2528, H10W 72/261, H10W 72/263, H10W 72/265, H10W 72/267, H10W 72/281, H10W 72/283, H10W 72/285, H10W 72/287, H10W 72/60, H10W 72/621,

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				H10W 72/622, H10W 72/623, H10W 72/624, H10W 72/625, H10W 72/627, H10W 72/631, H10W 72/634, H10W 72/635, H10W 72/637, H10W 72/641, H10W 72/645, H10W 72/647, H10W 72/642, H10W 72/643, H10W 72/646, H10W 72/6478, H10W 72/651, H10W 72/652, H10W 72/653, H10W 72/6528, H10W 72/655, H10W 72/657, H10W 72/681, H10W 72/683, H10W 72/685, H10W 72/691
N	H10W 72/221	2	{Structures or relative sizes}	
N	H10W 72/222	3	{Multilayered bumps, e.g. a coating on top and side surfaces of a bump core}	
N	H10W 72/223	4	{characterised by the structure of the outermost layers, e.g. multilayered coatings}	
N	H10W 72/224	3	{Bumps having multiple side-by-side cores}	
N	H10W 72/225	3	{Bumps having a filler embedded in a matrix}	
N	H10W 72/227	3	{Multiple bumps having different sizes}	
N	H10W 72/228	3	{Multiple bumps having different structures}	
N	H10W 72/231	2	{Shapes}	
N	H10W 72/232	3	{Plan-view shape, i.e. in top view}	
N	H10W 72/234	3	{Cross-sectional shape, i.e. in side view}	
N	H10W 72/235	3	{of outermost layers of multilayered bumps, e.g. bump coating not being conformal on a bump core}	
N	H10W 72/237	3	{Multiple bump connectors having different shapes}	
N	H10W 72/241	2	{Dispositions, e.g. layouts}	
N	H10W 72/242	3	{relative to the surface, e.g. recessed, protruding}	
N	H10W 72/244	3	{relative to underlying supporting features, e.g. bond pads, RDLs or vias}	
N	H10W 72/245	3	{of outermost layers of multilayered bumps, e.g. bump coating being only on a part of a bump core}	
N	H10W 72/247	3	{Dispositions of multiple bumps}	
N	H10W 72/248	4	{Top-view layouts, e.g. mirror arrays}	
N	H10W 72/251	2	{Materials}	

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N	H10W 72/252	3	{comprising solid metals or solid metalloids, e.g. PbSn, Ag or Cu}	
N	H10W 72/2524	4	{Eutectic alloys}	
N	H10W 72/2528	4	{Intermetallic compounds}	
N	H10W 72/253	3	{not comprising solid metals or solid metalloids, e.g. polymers or ceramics}	
N	H10W 72/255	3	{of outermost layers of multilayered bumps, e.g. material of a coating}	
N	H10W 72/257	3	{Multiple bump connectors having different materials}	
N	H10W 72/261	2	{Functions other than electrical connecting}	
N	H10W 72/263	3	{Providing mechanical bonding or support, e.g. dummy bumps}	
N	H10W 72/265	3	{Providing thermal transfer, e.g. thermal bumps}	
N	H10W 72/267	3	{Multiple bump connectors having different functions}	
N	H10W 72/281	2	{Auxiliary members}	
N	H10W 72/283	3	{Reinforcing structures, e.g. bump collars}	
N	H10W 72/285	3	{Alignment aids, e.g. alignment marks}	
N	H10W 72/287	3	{Flow barriers}	
N	H10W 72/29	2	Bond pads specially adapted therefor	
Q	H10W 72/30	1	Die-attach connectors	H10W 72/014, H10W 72/074, H10W 72/30, H10W 72/321, H10W 72/322, H10W 72/323, H10W 72/324, H10W 72/325 H10W 72/327, H10W 72/328, H10W 72/331, H10W 72/332, H10W 72/334, H10W 72/335, H10W 72/337, H10W 72/341, H10W 72/342, H10W 72/344, H10W 72/345, H10W 72/347, H10W 72/348, H10W 72/351, H10W 72/352, H10W 72/353, H10W 72/354, H10W 72/355, H10W 72/357, H10W 72/3524, H10W 72/3528, H10W 72/361, H10W 72/365, H10W 72/367, H10W 72/381, H10W 72/383, H10W 72/385, H10W 72/387, H10W 72/40, H10W 72/49

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N	H10W 72/321	2	{Structures or relative sizes of die-attach connectors}	
N	H10W 72/322	3	{Multilayered die-attach connectors, e.g. a coating on a top surface of a core}	
N	H10W 72/323	4	{characterised by the structures of the outermost layers, e.g. multilayered coatings}	
N	H10W 72/324	3	{Die-attach connectors having multiple side-by-side cores}	
N	H10W 72/325	3	{Die-attach connectors having a filler embedded in a matrix}	
N	H10W 72/327	3	{Multiple die-attach connectors having different sizes}	
N	H10W 72/328	3	{Multiple die-attach connectors having different structures}	
N	H10W 72/331	2	{Shapes of die-attach connectors}	
N	H10W 72/332	3	{Plan-view shape, i.e. in top view}	
N	H10W 72/334	3	{Cross-sectional shape, i.e. in side view}	
N	H10W 72/335	3	{of outermost layers of multilayered die-attach connectors, e.g. coating not being conformal on a core}	
N	H10W 72/337	3	{Multiple die-attach connectors having different shapes}	
N	H10W 72/341	2	{Dispositions of die-attach connectors, e.g. layouts}	
N	H10W 72/342	3	{relative to the surface, e.g. recessed, protruding}	
N	H10W 72/344	3	{relative to underlying supporting features, e.g. bond pads, RDLs or vias}	
N	H10W 72/345	3	{of outermost layers of multilayered die-attach connectors, e.g. coating being only on a part of a core}	
N	H10W 72/347	3	{Dispositions of multiple die-attach connectors}	
N	H10W 72/348	4	{Top-view layouts, e.g. mirror arrays}	
N	H10W 72/351	2	{Materials of die-attach connectors}	
N	H10W 72/352	3	{comprising metals or metalloids, e.g. solders}	
N	H10W 72/3524	4	{Eutectic alloys}	
N	H10W 72/3528	4	{Intermetallic compounds}	
N	H10W 72/353	3	{not comprising solid metals or solid metalloids, e.g. ceramics}	
N	H10W 72/354	4	{comprising polymers}	
N	H10W 72/355	3	{of outermost layers of multilayered die-attach connectors, e.g. material of a coating}	
N	H10W 72/357	3	{Multiple die-attach connectors having different materials}	

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N	H10W 72/361	2	{Functions of die-attach connectors, other than mechanically connecting}	
N	H10W 72/365	3	{Providing thermal transfer}	
N	H10W 72/367	3	{Multiple die-attach connectors having different functions}	
N	H10W 72/381	2	{Auxiliary members}	
N	H10W 72/383	3	{Reinforcing structures, e.g. collars}	
N	H10W 72/385	3	{Alignment aids, e.g. alignment marks}	
N	H10W 72/387	3	{Flow barriers}	
N	H10W 72/40	1	Anisotropic conductive adhesives	
N	H10W 72/49	2	Bond pads specially adapted therefor	
Q	H10W 72/50	1	Bond wires	H10W 72/50, H10W 72/521, H10W 72/522, H10W 72/523, H10W 72/524, H10W 72/525, H10W 72/527, H10W 72/528, H10W 72/531, H10W 72/533, H10W 72/534, H10W 72/535, H10W 72/537, H10W 72/536, H10W 72/5363, H10W 72/5366, H10W 72/5368, H10W 72/541, H10W 72/543, H10W 72/547, H10W 72/5434, H10W 72/5438, H10W 72/5473, H10W 72/5475, H10W 72/5445, H10W 72/5449, H10W 72/5453, H10W 72/551, H10W 72/552, H10W 72/5522, H10W 72/5524, H10W 72/5525, H10W 72/553, H10W 72/555, H10W 72/557, H10W 72/5528, H10W 72/581, H10W 72/583, H10W 72/585
N	H10W 72/521	2	{Structures or relative sizes of bond wires}	
N	H10W 72/522	3	{Multilayered bond wires, e.g. having a coating concentric around a core}	
N	H10W 72/523	4	{characterised by the structures of the outermost layers, e.g. multilayered coatings}	
N	H10W 72/524	3	{Bond wires having multiple distinct cores}	
N	H10W 72/525	3	{Bond wires having a filler embedded in a matrix}	
N	H10W 72/527	3	{Multiple bond wires having different sizes}	
N	H10W 72/528	3	{Multiple bond wires having different structures}	

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N	H10W 72/531	2	{Shapes of wire connectors}	
N	H10W 72/533	3	{Cross-sectional shape}	
N	H10W 72/534	4	{being rectangular}	
N	H10W 72/535	3	{Shapes of outermost layers of multilayered bond wires, e.g. coating not being conformal on a core}	
N	H10W 72/536	3	{the connected ends being ball-shaped}	
N	H10W 72/5363	3	{the connected ends being wedge-shaped}	
N	H10W 72/5366	3	{the bond wires having kinks}	
N	H10W 72/5368	3	{the bond wires having helical loops}	
N	H10W 72/537	3	{Multiple bond wires having different shapes}	
N	H10W 72/541	2	{Dispositions of bond wires}	
N	H10W 72/543	3	{of outermost layers of multilayered bond wires, e.g. coating being only on a part of a core}	
N	H10W 72/5434	3	{the connected ends being on auxiliary connecting means on bond pads, e.g. on other bond wires}	
N	H10W 72/5438	3	{the bond wires having multiple connections on the same bond pad}	
N	H10W 72/5445	3	{being orthogonal to a side surface of the chip, e.g. parallel arrangements}	
N	H10W 72/5449	3	{not being orthogonal to a side surface of the chip, e.g. fan-out arrangements}	
N	H10W 72/5453	3	{connecting between multiple bond pads on a chip, e.g. daisy chain}	
N	H10W 72/547	3	{Dispositions of multiple bond wires}	
N	H10W 72/5473	4	{multiple bond wires connected to a common bond pad}	
N	H10W 72/5475	4	{multiple bond wires connected to common bond pads at both ends of the wires}	
N	H10W 72/551	2	{Materials of bond wires}	
N	H10W 72/552	3	{comprising metals or metalloids, e.g. silver}	
N	H10W 72/5522	4	{comprising gold [Au]}	
N	H10W 72/5524	4	{comprising aluminium [Al]}	
N	H10W 72/5525	4	{comprising copper [Cu]}	
N	H10W 72/5527	4	{Eutectic alloys}	
N	H10W 72/5528	4	{Intermetallic compounds}	
N	H10W 72/553	3	{not comprising solid metals or solid metalloids, e.g. polymers, ceramics or liquids}	
N	H10W 72/555	3	{of outermost layers of multilayered bond wires, e.g. material of a coating}	

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N	H10W 72/557	3	{Multiple bond wires having different materials}	
N	H10W 72/581	2	{Auxiliary members, e.g. flow barriers}	
N	H10W 72/583	3	{Reinforcing structures}	
N	H10W 72/585	3	{Alignment aids, e.g. alignment marks}	
N	H10W 72/59	2	Bond pads specially adapted therefor	
Q	H10W 72/60	1	Strap connectors, e.g. thick copper clips for grounding of power devices	H10W 72/60, H10W 72/621, H10W 72/622, H10W 72/623, H10W 72/624, H10W 72/625, H10W 72/627, H10W 72/631, H10W 72/634, H10W 72/635, H10W 72/637, H10W 72/641, H10W 72/645, H10W 72/647, H10W 72/646, H10W 72/642, H10W 72/643, H10W 72/6478, H10W 72/651, H10W 72/652, H10W 72/653, H10W 72/6528, H10W 72/655, H10W 72/657, H10W 72/681, H10W 72/683, H10W 72/685, H10W 72/701
N	H10W 72/621	2	{Structures or relative sizes of strap connectors}	
N	H10W 72/622	3	{Multilayered strap connectors, e.g. having a coating on a lowermost surface of a core}	
N	H10W 72/623	4	{characterised by the structures of the outermost layers, e.g. multilayered coatings}	
N	H10W 72/624	3	{Strap connectors having multiple distinct cores}	
N	H10W 72/625	3	{Strap connectors having a filler embedded in a matrix}	
N	H10W 72/627	3	{Multiple strap connectors having different structures or shapes}	
N	H10W 72/631	2	{Shapes of strap connectors}	
N	H10W 72/634	3	{Cross-sectional shape}	
N	H10W 72/635	3	{of outermost layers of multilayered strap connectors, e.g. coating not being conformal on a core}	
N	H10W 72/637	3	{Multiple strap connectors having different shapes}	
N	H10W 72/641	2	{Dispositions of strap connectors}	
N	H10W 72/642	3	{being orthogonal to a side surface of the chip, e.g. in parallel arrangements}	

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N	H10W 72/643	3	{not being orthogonal to a side surface of the chip, e.g. in fan-out arrangements}	
N	H10W 72/644	3	{connecting directly between multiple pads on a chip}	
N	H10W 72/645	3	{of outermost layers of multilayered strap connectors, e.g. coating being only on a part of a core}	
N	H10W 72/646	3	{the connected ends being on auxiliary connecting means on bond pads, e.g. on a bump connector}	
N	H10W 72/647	3	{Dispositions of multiple strap connectors}	
N	H10W 72/6478	4	{multiple strap connectors connecting to a common bond pad}	
N	H10W 72/651	2	{Materials of strap connectors}	
N	H10W 72/652	3	{comprising metals or metalloids, e.g. silver}	
N	H10W 72/6524	4	{Eutectic alloys}	
N	H10W 72/6528	4	{Intermetallic compounds}	
N	H10W 72/653	3	{not comprising solid metals or solid metalloids, e.g. polymers, ceramics or liquids}	
N	H10W 72/655	3	{of outermost layers of multilayered strap connectors, e.g. material of a coating}	
N	H10W 72/657	3	{Multiple strap connectors having different materials}	
N	H10W 72/681	2	{Auxiliary members, e.g. flow barriers}	
N	H10W 72/683	3	{Reinforcing structures, e.g. bump collars}	
N	H10W 72/685	3	{Alignment aids, e.g. alignment marks}	
N	H10W 72/691	2	{Bond pads specially adapted therefor}	
N	H10W 72/701	1	{Tape-automated bond [TAB] connectors}	
N	H10W 72/709	2	{Bond pads specially adapted therefor}	
Q	H10W 72/801	1	{Interconnections on sidewalls of containers}	H10W 72/801, H10W 72/812
N	H10W 72/812	1	{Interconnections on sidewalls of encapsulations, e.g. conductive traces on molded resins}	
Q	H10W 72/823	1	{Interconnections through encapsulations, e.g. pillars through molded resin on a lateral side a chip}	H10W 20/20, H10W 20/211, H10W 20/215, H10W 20/222, H10W 72/823, H10W 76/132, H10W 76/134, H10W 76/153, H10W 76/157, H10W 76/165
N	H10W 72/834	1	{Interconnections on sidewalls of chips}	
N	H10W 72/851	1	{Dispositions of multiple connectors or interconnections}	

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N	H10W 72/853	2	{On the same surface}	
N	H10W 72/856	3	{Bump connectors and die-attach connectors (bumps embedded in underfills H10W 74/15)}	
N	H10W 72/859	3	{Bump connectors and bond wires}	
N	H10W 72/862	3	{Bump connectors and strap connectors}	
N	H10W 72/865	3	{Die-attach connectors and bond wires}	
N	H10W 72/868	3	{Die-attach connectors and strap connectors}	
N	H10W 72/871	3	{Bond wires and strap connectors}	
N	H10W 72/874	2	{On different surfaces}	
N	H10W 72/877	3	{Bump connectors and die-attach connectors}	
N	H10W 72/879	3	{Bump connectors and bond wires}	
N	H10W 72/881	3	{Bump connectors and strap connectors}	
N	H10W 72/884	3	{Die-attach connectors and bond wires}	
N	H10W 72/886	3	{Die-attach connectors and strap connectors}	
N	H10W 72/889	3	{Bond wires and strap connectors}	
Q	H10W 72/90	1	Bond pads, in general	H10W 72/90, H10W 72/921, H10W 72/922, H10W 72/9223, H10W 72/9226, H10W 72/923, H10W 72/9232, H10W 72/924, H10W 72/925, H10W 72/926, H10W 72/927, H10W 72/931, H10W 72/932, H10W 72/934, H10W 72/936, H10W 72/941, H10W 72/9413, H10W 72/9415, H10W 72/942, H10W 72/944, H10W 72/9445, H10W 72/951, H10W 72/952, H10W 72/953, H10W 72/957, H10W 72/9524, H10W 72/9528, H10W 72/961, H10W 72/963, H10W 72/965, H10W 72/967, H10W 72/981, H10W 72/983, H10W 72/985, H10W 72/987
N	H10W 72/921	2	{Structures or relative sizes of bond pads}	
N	H10W 72/922	3	{Bond pads being integral with underlying chip-level interconnections}	
N	H10W 72/9223	4	{with redistribution layers [RDL]}	
N	H10W 72/9226	4	{with via interconnections}	

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N	H10W 72/923	3	{Bond pads having multiple stacked layers}	
N	H10W 72/9232	4	{with additional elements interposed between layers}	
N	H10W 72/924	3	{Bond pads having multiple side-by-side cores}	
N	H10W 72/925	3	{Bond pads having a filler embedded in a matrix}	
N	H10W 72/926	3	{Multiple bond pads having different sizes}	
N	H10W 72/927	3	{Multiple bond pads having different structures}	
N	H10W 72/931	2	{Shapes of bond pads}	
N	H10W 72/932	3	{Plan-view shape, i.e. in top view}	
N	H10W 72/934	3	{Cross-sectional shape, i.e. in side view}	
N	H10W 72/936	3	{Multiple bond pads having different shapes}	
N	H10W 72/941	2	{Dispositions of bond pads}	
N	H10W 72/9413	3	{on encapsulations}	
N	H10W 72/9415	3	{relative to the surface, e.g. recessed, protruding}	
N	H10W 72/942	3	{relative to underlying supporting features, e.g. bond pads, RDLs or vias}	
N	H10W 72/944	3	{Dispositions of multiple bond pads}	
N	H10W 72/9445	4	{Top-view layouts, e.g. mirror arrays}	
N	H10W 72/951	2	{Materials of bond pads}	
N	H10W 72/952	3	{comprising metals or metalloids, e.g. PbSn, Ag or Cu}	
N	H10W 72/9524	4	{Eutectic alloys}	
N	H10W 72/9528	4	{Intermetallic compounds}	
N	H10W 72/953	3	{not comprising solid metals or solid metalloids, e.g. polymers, ceramics or liquids}	
N	H10W 72/957	3	{Multiple bond pads having different materials}	
N	H10W 72/961	2	{Functions of bonds pads}	
N	H10W 72/963	3	{Providing mechanical bonding or support, e.g. dummy bond pads}	
N	H10W 72/965	3	{Providing thermal transfer}	
N	H10W 72/967	3	{Multiple bond pads having different functions}	
N	H10W 72/981	2	{Auxiliary members, e.g. spacers}	
N	H10W 72/983	3	{Reinforcing structures, e.g. collars}	
N	H10W 72/985	3	{Alignment aids, e.g. alignment marks}	
N	H10W 72/987	3	{Flow barriers}	
N	H10W 74/00	0	Encapsulations, e.g. protective coatings	
N	H10W 74/01	1	Manufacture or treatment	

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N	H10W 74/012	2	{of encapsulations on active surfaces of flip-chip devices, e.g. forming underfills}	
N	H10W 74/014	2	{using batch processing}	
N	H10W 74/016	2	{using moulds}	
N	H10W 74/017	3	{Auxiliary layers for moulds, e.g. release layers or layers preventing residue}	
N	H10W 74/019	2	{using temporary auxiliary substrates (H10W 74/017 takes precedence)}	
Q	H10W 74/10	1	characterised by their shape or disposition	H10W 74/10, H10W 74/15
N	H10W 74/111	2	{the semiconductor body being completely enclosed}	
N	H10W 74/114	3	{by a substrate and the encapsulations}	
N	H10W 74/117	4	{the substrate having spherical bumps for external connection}	
N	H10W 74/121	3	{by multiple encapsulations, e.g. by a thin protective coating and a thick encapsulation}	
N	H10W 74/124	3	{the encapsulations having cavities other than that occupied by chips}	
N	H10W 74/127	3	{characterised by arrangements for sealing or adhesion}	
N	H10W 74/129	3	{forming a chip-scale package [CSP]}	
N	H10W 74/131	2	{the semiconductor body being only partially enclosed}	
N	H10W 74/134	3	{the encapsulations being in grooves in the semiconductor body}	
N	H10W 74/137	3	{the encapsulations being directly on the semiconductor body (H10W 74/134 takes precedence)}	
N	H10W 74/141	3	{the encapsulations being on at least the sidewalls of the semiconductor body}	
N	H10W 74/142	3	{the encapsulations exposing the passive side of the semiconductor body}	
N	H10W 74/144	3	{the encapsulations comprising foils}	
N	H10W 74/147	3	{the encapsulations being multilayered}	
N	H10W 74/15	2	on active surfaces of flip-chip devices, e.g. underfills	
N	H10W 74/40	1	characterised by their materials	
N	H10W 74/43	2	comprising oxides, nitrides or carbides, e.g. ceramics or glasses	
N	H10W 74/47	2	comprising organic materials, e.g. plastics or resins	
N	H10W 74/473	3	{containing a filler}	
N	H10W 74/476	3	{Organic materials comprising silicon}	
N	H10W 74/481	2	{comprising semiconductor materials}	

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N	H10W 76/00	0	Containers; Fillings or auxiliary members therefor; Seals	
N	H10W 76/01	1	Manufacture or treatment	
N	H10W 76/05	2	Providing fillings in containers, e.g. gas filling	
N	H10W 76/10	1	Containers or parts thereof	
N	H10W 76/12	2	characterised by their shape	
N	H10W 76/13	3	Containers comprising a conductive base serving as an interconnection	
N	H10W 76/132	4	having other interconnections through an insulated passage in the conductive base	
N	H10W 76/134	4	having other interconnections parallel to the conductive base	
N	H10W 76/136	4	having other interconnections perpendicular to the conductive base	
N	H10W 76/138	4	having another interconnection being formed by a cover plate parallel to the conductive base, e.g. sandwich type	
N	H10W 76/15	3	Containers comprising an insulating or insulated base	
N	H10W 76/153	4	having interconnections in passages through the insulating or insulated base	
N	H10W 76/157	4	having interconnections parallel to the insulating or insulated base	
N	H10W 76/161	3	{Containers comprising no base}	
N	H10W 76/165	3	{characterised by interconnections through the top surface of the containers, e.g. in a metal cap}	
N	H10W 76/167	3	{the container walls comprising an aperture, e.g. for pressure control}	
N	H10W 76/17	2	characterised by their materials	
N	H10W 76/18	3	Insulating materials, e.g. resins, glasses or ceramics	
N	H10W 76/40	1	Fillings or auxiliary members in containers, e.g. centering rings (fillings or auxiliary members for thermal protection or control in containers or encapsulations H10W 40/70)	
N	H10W 76/42	2	Fillings	
N	H10W 76/43	3	Gaseous fillings	
N	H10W 76/45	3	Liquid fillings	
N	H10W 76/47	3	Solid or gel fillings	
N	H10W 76/48	3	Fillings including materials for absorbing or reacting with moisture or other undesired substances	
Q	H10W 76/60	1	Seals	H10W 76/60, H10W 76/63, H10W 76/67

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N	H10W 76/63	2	characterised by their shape or disposition, e.g. between cap and walls of a container	
N	H10W 76/67	2	characterised by their materials	
N	H10W 78/00	0	Detachable holders for supporting packaged chips in operation	
N	H10W 80/00	0	Direct bonding of chips, wafers or substrates	
N	H10W 80/011	1	{Manufacture or treatment of pads or other interconnections to be direct bonded}	
N	H10W 80/016	2	{Cleaning}	
N	H10W 80/023	2	{Applying a coating on the bonding area}	
N	H10W 80/031	2	{Changing or setting shapes of the pads}	
N	H10W 80/033	3	{by chemical means, e.g. etching}	
N	H10W 80/035	3	{by heating, e.g. melting or causing diffusion}	
N	H10W 80/037	3	{by mechanical treatment, e.g. by cutting, pressing or stamping}	
N	H10W 80/041	2	{Thermally treating}	
N	H10W 80/102	1	{Controlling the environment during the bonding, e.g. the temperature or pressure}	
N	H10W 80/161	1	{Aligning}	
N	H10W 80/163	2	{using active alignment, e.g. detecting marks and correcting position}	
N	H10W 80/165	2	{using passive alignment, e.g. using self-alignment}	
N	H10W 80/168	2	{using guiding structures}	
N	H10W 80/211	1	{using auxiliary members, e.g. aids for protecting the bonding area}	
N	H10W 80/301	1	{Bonding techniques, e.g. hybrid bonding}	
N	H10W 80/312	2	{characterised by the direct bonding of electrically conductive pads}	
N	H10W 80/314	2	{characterized by direct bonding of pads or other interconnections}	
N	H10W 80/327	2	{characterised by the direct bonding of insulating parts, e.g. of silicon oxide layers}	
N	H10W 80/331	2	{characterised by the application of energy for connecting}	
N	H10W 80/333	3	{Compression bonding}	
N	H10W 80/334	4	{Thermocompression bonding}	
N	H10W 80/335	4	{Ultrasonic bonding}	
N	H10W 80/337	3	{causing reflow}	
N	H10W 80/338	3	{using EM radiation or electron beams, e.g. using lasers}	
N	H10W 80/339	3	{using integrated means for heating, e.g. embedded heater}	
N	H10W 80/341	2	{Anodic bonding}	

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N	H10W 80/701	1	{characterised by the pads after the direct bonding}	
N	H10W 80/721	2	{having structure or size changed during the connecting}	
N	H10W 80/732	2	{having shape changed during the connecting}	
N	H10W 80/743	2	{having disposition changed during the connecting}	
N	H10W 80/754	2	{having material changed during the connecting}	
Q	H10W 90/00	0	Package configurations	H10B 80/00, H10D 80/00, H10D 80/20, H10D 80/211, H10D 80/213, H10D 80/215, H10D 80/231, H10D 80/251, H10D 80/30, H10F 39/90, H10F 39/95, H10H 29/20, H10H 29/24, H10H 29/30, H10H 29/32, H10H 29/34, H10H 29/345, H10H 29/352, H10H 29/362, H10H 29/37, H10H 29/39, H10H 29/41, H10H 29/45, H10H 29/49, H10K 19/00, H10K 19/10, H10K 19/20, H10K 19/201, H10K 19/202, H10K 19/80, H10K 19/901, H10K 39/601, H10K 39/621, H10K 59/90, H10K 59/95, H10K 65/00, H10W 90/00, H10W 90/10, H10W 90/15, H10W 90/155, H10W 90/20, H10W 90/22, H10W 90/231, H10W 90/24, H10W 90/26, H10W 90/271, H10W 90/275, H10W 90/28, H10W 90/284, H10W 90/288, H10W 90/291, H10W 90/293, H10W 90/295, H10W 90/701, H10W 90/721, H10W 90/722, H10W 90/723, H10W 90/724, H10W 90/725, H10W 90/726, H10W 90/727, H10W 90/728, H10W 90/729,

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				H10W 90/731, H10W 90/732, H10W 90/733, H10W 90/734, H10W 90/735, H10W 90/736, H10W 90/737, H10W 90/738, H10W 90/739, H10W 90/751, H10W 90/752, H10W 90/753, H10W 90/754, H10W 90/755, H10W 90/756, H10W 90/757, H10W 90/758, H10W 90/759, H10W 90/761, H10W 90/762, H10W 90/763, H10W 90/764, H10W 90/765, H10W 90/766, H10W 90/767, H10W 90/768, H10W 90/769, H10W 90/791, H10W 90/792, H10W 90/794, H10W 90/796, H10W 90/798, H10W 90/811
N	H10W 90/10	1	Configurations of laterally-adjacent chips	
N	H10W 90/15	2	the laterally-adjacent chips having different thicknesses than each other	
N	H10W 90/155	2	{the laterally-adjacent chips comprising dummy chips}	
N	H10W 90/20	1	Configurations of stacked chips	
N	H10W 90/22	2	the stacked chips being on both top and bottom sides of a package substrate, interposer or RDL	
N	H10W 90/231	2	{the stacked chips being on both top and bottom sides of an auxiliary carrier having no electrical connection structure}	
N	H10W 90/24	2	at least one of the stacked chips being laterally offset from a neighbouring stacked chip, e.g. chip stacks having a staircase shape	
N	H10W 90/26	2	the stacked chips being of the same size without any chips being laterally offset, e.g. chip stacks having a rectangular shape	
N	H10W 90/271	2	{the chips having passive surfaces facing each other, i.e. in a back-to-back arrangement}	
N	H10W 90/275	2	{the stacked chips comprising dummy chips}	
N	H10W 90/28	2	the stacked chips having different sizes, e.g. chip stacks having a pyramidal shape	
N	H10W 90/284	2	{characterised by structural arrangements for measuring or testing}	

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N	H10W 90/288	2	{characterised by arrangements for thermal management of the stacked chips}	
N	H10W 90/291	2	{characterised by containers, encapsulations, or other housings for the stacked chips}	
N	H10W 90/293	2	{characterised by non-galvanic coupling between the chips, e.g. capacitive coupling}	
N	H10W 90/295	3	{optical coupling}	
N	H10W 90/297	2	{characterised by the through-semiconductor vias [TSVs] in the stacked chips}	
N	H10W 90/401	1	{characterised by multiple insulating or insulated package substrates, interposers or RDLs}	
Q	H10W 90/701	1	{characterised by the relative positions of pads or connectors relative to package parts}	H10W 90/701, H10W 90/724, H10W 90/725, H10W 90/7295, H10W 90/754, H10W 90/755, H10W 90/764, H10W 90/765
N	H10W 90/721	2	{of bump connectors}	
N	H10W 90/722	3	{between stacked chips}	
N	H10W 90/723	3	{between laterally-adjacent chips}	
Q	H10W 90/724	3	{between a chip and a stacked insulating package substrate, interposer or RDL}	H10W 90/724, H10W 90/726
N	H10W 90/725	3	{between a chip and a laterally-adjacent insulating package substrate, interposer or RDL}	
N	H10W 90/726	3	{between a chip and a stacked lead frame, conducting package substrate or heat sink}	
N	H10W 90/727	3	{between a chip and a laterally-adjacent lead frame, conducting package substrate or heat sink}	
N	H10W 90/728	3	{between a chip and a stacked discrete passive device, e.g. resistors, capacitors or inductors}	
N	H10W 90/729	3	{between a chip and a laterally-adjacent discrete passive device}	
N	H10W 90/7295	3	{on the rear surface of insulating package substrates, interposers or RDLs, for connection outside of the package, e.g. ball grid array [BGA] bumps}	
N	H10W 90/731	2	{of die-attach connectors}	
N	H10W 90/732	3	{between stacked chips}	
N	H10W 90/733	3	{between laterally-adjacent chips}	
N	H10W 90/734	3	{between a chip and a stacked insulating package substrate, interposer or RDL}	

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N	H10W 90/735	3	{between a chip and a laterally-adjacent insulating package substrate, interposer or RDL}	
N	H10W 90/736	3	{between a chip and a stacked lead frame, conducting package substrate or heat sink}	
N	H10W 90/737	3	{between a chip and a laterally-adjacent lead frame, conducting package substrate or heat sink}	
N	H10W 90/738	3	{between a chip and a stacked discrete passive device}	
N	H10W 90/739	3	{between a chip and a laterally-adjacent discrete passive devices}	
N	H10W 90/751	2	{of bond wires}	
N	H10W 90/752	3	{between stacked chips}	
N	H10W 90/753	3	{between laterally-adjacent chips}	
Q	H10W 90/754	3	{between a chip and a stacked insulating package substrate, interposer or RDL}	H10W 90/754, H10W 90/756
N	H10W 90/755	3	{between a chip and a laterally-adjacent insulating package substrate, interpose or RDL}	
N	H10W 90/756	3	{between a chip and a stacked lead frame, conducting package substrate or heat sink}	
N	H10W 90/757	3	{between a chip and a laterally-adjacent lead frame, conducting package substrate or heat sink}	
N	H10W 90/758	3	{between a chip and a stacked discrete passive device}	
N	H10W 90/759	3	{between a chip and a laterally-adjacent discrete passive device}	
N	H10W 90/761	2	{of strap connectors}	
N	H10W 90/762	3	{between stacked chips}	
N	H10W 90/763	3	{between laterally-adjacent chips}	
N	H10W 90/764	3	{between a chip and a stacked insulating package substrate, interposer or RDL}	
N	H10W 90/765	3	{between a chip and a laterally-adjacent insulating package substrate, interposer or RDL}	
N	H10W 90/766	3	{between a chip and a stacked lead frame, conducting package substrate or heat sink}	
N	H10W 90/767	3	{between a chip and a laterally-adjacent lead frame, conducting package substrate or heat sink}	
N	H10W 90/768	3	{between a chip and a stacked discrete passive device}	
N	H10W 90/769	3	{between a chip and a laterally-adjacent discrete passive device}	
N	H10W 90/791	2	{of direct-bonded pads}	

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N	H10W 90/792	3	{between multiple chips}	
N	H10W 90/794	3	{between a chip and a stacked insulating package substrate, interposer or RDL}	
N	H10W 90/796	3	{between a chip and a stacked lead frame, conducting package substrate or heat sink}	
N	H10W 90/798	3	{between a chip and a stacked discrete passive device}	
N	H10W 90/811	1	{Multiple chips on leadframes}	
N	H10W 95/00	0	Packaging processes not covered by the other groups of this subclass	
Q	H10W 99/00	0	Subject matter not provided for in other groups of this subclass	H10W 40/00, H10W 40/01, H10W 42/00, H10W 70/00, H10W 70/01, H10W 70/02, H10W 70/04, H10W 70/05, H10W 70/06, H10W 70/08, H10W 70/09, H10W 74/01, H10W 76/01, H10W 95/00, H10W 99/00

*N = new entries where reclassification into entries is involved; C = entries with modified file scope where reclassification of documents from the entries is involved; Q = new entries which are firstly populated with documents via administrative transfers from deleted (D) entries. Afterwards, the transferred documents into the Q entry will either stay or be moved to more appropriate entries, as determined by intellectual reclassification; T = existing entries with enlarged file scope, which receive documents from C or D entries, e.g. when a limiting reference is removed from the entry title; M = entries with no change to the file scope (no reclassification); D = deleted entries; F = frozen entries will be deleted once reclassification of documents from the entries is completed; U = entries that are unchanged.

NOTES:

- **No {curly brackets} are used for titles in CPC only subclasses, e.g. C12Y, A23Y; 2000 series symbol titles of groups found at the end of schemes (orthogonal codes); or the Y section titles. The {curly brackets} are used for 2000 series symbol titles found interspersed throughout the main trunk schemes (breakdown codes).
- U groups: it is obligatory to display the required “anchor” symbol (U group), i.e. the entry immediately preceding a new group or an array of new groups to be created (in case new groups are not clearly subgroups of C-type groups). Always include the symbol, indent level and title of the U group in the table above.
- All entry types should be included in the scheme changes table above for better understanding of the overall scheme change picture. Symbol, indent level, and title are required for all types.
- “Transferred to” column must be completed for all C, D, F, and Q type entries. F groups will be deleted once reclassification is completed.
- When multiple symbols are included in the “Transferred to” column, avoid using ranges of symbols in order to be as precise as possible.
- For administrative transfer of documents, the following text should be used: “<administrative transfer to XX>”, “<administrative transfer to XX and YY simultaneously>”, or “<administrative transfer to XX, YY, ...and ZZ simultaneously>” when administrative transfer of the same documents is to more than one place.
- Administrative transfer to main trunk groups is assumed to be the source allocation type, unless otherwise indicated.

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- Administrative transfer to 2000/Y series groups is assumed to be “additional information”.
- If needed, instructions for allocation type should be indicated within the angle brackets using the abbreviations “ADD” or “INV”: <administrative transfer to XX ADD>, <administrative transfer to XX INV>, or <administrative transfer to XX ADD, YY INV, ... and ZZ ADD simultaneously>.
- In certain situations, the “D” entries of 2000-series or Y-series groups may not require a destination (“Transferred to”) symbol, however it is required to specify “<no transfer>” in the “Transferred to” column for such cases.
- For finalization projects, the deleted “F” symbols should have <no transfer> in the “Transferred to” column.
- For more details about the types of scheme change, see CPC Guide.

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B. New, Modified or Deleted Warning notice(s)**SUBCLASS H01L - SEMICONDUCTOR DEVICES NOT COVERED BY CLASS H10**

Type*	Location	Old Warning notice	New/Modified Warning
D	H01L 25/04	Group H01L 25/04 is impacted by reclassification into groups H10N 19/00, H10N 39/00, H10N 59/00, H10N 69/00, H10N 79/00 and H10N 89/00. All groups listed in this Warning should be considered in order to perform a complete search.	
D	H01L 25/065	Group H01L 25/065 is impacted by reclassification into groups H10B 80/00, H10K 39/10, H10K 39/12, H10K 39/15, H10K 39/18, H10K 39/601, H10K 39/621, H10K 59/90, H10K 59/95, H10N 19/00, H10N 39/00, H10N 59/00, H10N 69/00, H10N 79/00 and H10N 89/00. All groups listed in this Warning should be considered in order to perform a complete search.	
D	H01L 25/0652	Group H01L 25/0652 is impacted by reclassification into groups H10B 80/00, H10K 39/10, H10K 39/12, H10K 39/15, H10K 39/18, H10K 39/601, H10K 39/621, H10K 59/90, H10K 59/95, H10N 19/00, H10N 39/00, H10N 59/00, H10N 69/00, H10N 79/00 and H10N 89/00. All groups listed in this Warning should be considered in order to perform a complete search.	
D	H01L 25/0655	Group H01L 25/0655 is impacted by reclassification into groups H10B 80/00, H10K 39/10, H10K 39/12, H10K 39/15, H10K 39/18, H10K 39/601, H10K 39/621, H10K 59/90, H10K 59/95, H10N 19/00, H10N 39/00, H10N 59/00, H10N 69/00, H10N 79/00 and H10N 89/00. All groups listed in this Warning should be considered in order to perform a complete search.	
D	H01L 25/0657	Group H01L 25/0657 is impacted by reclassification into groups H10B 80/00, H10K 39/10, H10K 39/12, H10K 39/15, H10K 39/18, H10K 39/601, H10K 39/621, H10K 59/90, H10K 59/95, H10N 19/00, H10N 39/00, H10N 59/00, H10N 69/00, H10N 79/00 and H10N 89/00. All groups listed in this Warning should be considered in order to perform a complete search.	
D	H01L 25/16	Group H01L 25/16 is impacted by reclassification into groups H10B 80/00,	

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		H10K 39/10, H10K 39/12, H10K 39/15, H10K 39/18, H10K 39/601, H10K 39/621, H10K 59/90, H10K 59/95, H10N 19/00, H10N 39/00, H10N 59/00, H10N 69/00, H10N 79/00 and H10N 89/00. All groups listed in this Warning should be considered in order to perform a complete search.	
D	H01L 25/162	Group H01L 25/162 is impacted by reclassification into groups H10B 80/00, H10K 39/10, H10K 39/12, H10K 39/15, H10K 39/18, H10K 39/601, H10K 39/621, H10K 59/90, H10K 59/95, H10N 19/00, H10N 39/00, H10N 59/00, H10N 69/00, H10N 79/00 and H10N 89/00. All groups listed in this Warning should be considered in order to perform a complete search.	
D	H01L 25/165	Group H01L 25/165 is impacted by reclassification into groups H10B 80/00, H10K 39/10, H10K 39/12, H10K 39/15, H10K 39/18, H10K 39/601, H10K 39/621, H10K 59/90, H10K 59/95, H10N 19/00, H10N 39/00, H10N 59/00, H10N 69/00, H10N 79/00 and H10N 89/00. All groups listed in this Warning should be considered in order to perform a complete search.	
D	H01L 25/167	Group H01L 25/167 is impacted by reclassification into groups H10B 80/00, H10K 39/10, H10K 39/12, H10K 39/15, H10K 39/18, H10K 39/601, H10K 39/621, H10K 59/90, H10K 59/95, H10N 19/00, H10N 39/00, H10N 59/00, H10N 69/00, H10N 79/00 and H10N 89/00. All groups listed in this Warning should be considered in order to perform a complete search.	
D	H01L 25/18	Group H01L 25/18 is impacted by reclassification into groups H10B 80/00, H10K 19/00, H10K 39/10, H10K 39/12, H10K 39/15, H10K 39/18, H10K 39/601, H10K 39/621, H10K 59/90, H10K 59/95, H10K 65/00, H10N 19/00, H10N 39/00, H10N 59/00, H10N 69/00, H10N 79/00 and H10N 89/00. All groups listed in this Warning should be considered in order to perform a complete search.	

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SUBCLASS H10B - ELECTRONIC MEMORY DEVICES

<u>Type*</u>	<u>Location</u>	<u>Old Warning notice</u>	<u>New/Modified Warning</u>
M	H10B 80/00	Group H10B 80/00 is incomplete pending reclassification of documents from groups H01L 25/065, H01L 25/0652, H01L 25/0655, H01L 25/0657, H01L 25/16, H01L 25/162, H01L 25/165, H01L 25/167 and H01L 25/18. All groups listed in this Warning should be considered in order to perform a complete search.	Group H10B 80/00 is incomplete pending reclassification of documents from group H10W 90/00. Groups H10W 90/00 and H10B 80/00 should be considered in order to perform a complete search.

SUBCLASS H10D - INORGANIC ELECTRIC SEMICONDUCTOR DEVICES

<u>Type*</u>	<u>Location</u>	<u>Old Warning notice</u>	<u>New/Modified Warning</u>
N	H10D 80/00		Group H10D 80/00 is incomplete pending reclassification of documents from group H10W 90/00. Groups H10W 90/00 and H10D 80/00 should be considered in order to perform a complete search.

SUBCLASS H10F - INORGANIC SEMICONDUCTOR DEVICES SENSITIVE TO INFRARED RADIATION, LIGHT, ELECTROMAGNETIC RADIATION OF SHORTER WAVELENGTH OR CORPUSCULAR RADIATION

<u>Type*</u>	<u>Location</u>	<u>Old Warning notice</u>	<u>New/Modified Warning</u>
N	H10F 39/90		Groups H10F 39/90 and H10F 39/95 are incomplete pending reclassification of documents from group H10W 90/00. Groups H10W 90/00, H10F 39/90 and H10F 39/95 should be considered in order to perform a complete search.

SUBCLASS H10H - INORGANIC LIGHT-EMITTING SEMICONDUCTOR DEVICES HAVING POTENTIAL BARRIERS

<u>Type*</u>	<u>Location</u>	<u>Old Warning notice</u>	<u>New/Modified Warning</u>
N	H10H 29/20		Groups H10H 29/20 and H10H 29/24 are incomplete pending reclassification of documents from group H10W 90/00. Groups H10W 90/00, H10H 29/20 and H10H 29/24 should be considered in order to perform a complete search.

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M	H10H 29/30	Groups H10H 29/30, H10H 29/32, H10H 29/34, H10H 29/345, H10H 29/352, H10H 29/362, H10H 29/37, H10H 29/39, H10H 29/41 and H10H 29/45 are incomplete pending reclassification of documents from group H10H 29/142	Groups H10H 29/30, H10H 29/32, H10H 29/34, H10H 29/345, H10H 29/352, H10H 29/362, H10H 29/37, H10H 29/39, H10H 29/41, H10H 29/45 and H10H 29/49 are incomplete pending reclassification of documents from group H10W 90/00. All groups listed in this Warning should be considered in order to perform a complete search.

SUBCLASS H10W - GENERIC PACKAGES, INTERCONNECTIONS, CONNECTORS OR OTHER CONSTRUCTIONAL DETAILS OF DEVICES COVERED BY CLASS H10

<u>Type*</u>	<u>Location</u>	<u>Old Warning notice</u>	<u>New/Modified Warning</u>
N	H10W 20/023		Group H10W 20/023 is impacted by reclassification into groups H10W 20/0234, H10W 20/0238, H10W 20/0242, H10W 20/0245, H10W 20/0249, H10W 20/0253, H10W 20/0257, H10W 20/0261 and H10W 20/0265. All groups listed in this Warning should be considered in order to perform a complete search.
N	H10W 20/0234		Groups H10W 20/0234 - H10W 20/0265 are incomplete pending reclassification of documents from group H10W 20/023. Groups H10W 20/023 and H10W 20/0234 - H10W 20/0265 should be considered in order to perform a complete search.
N	H10W 20/037		Group H10W 20/037 is impacted by reclassification into group H10W 20/0372. Groups H10W 20/037 and H10W 20/0372 should be considered in order to perform a complete search
N	H10W 20/0372		Group H10W 20/0372 is incomplete pending reclassification of documents from group H10W 20/037. Groups H10W 20/037 and H10W 20/0372 should be considered in order to perform a complete search.
N	H10W 20/056		Group H10W 20/056 is impacted by reclassification into group H10W 20/0595. Groups H10W 20/056 and H10W 20/0595 should be considered in order to perform a complete search.
N	H10W 20/0595		Group H10W 20/0595 is incomplete pending reclassification of documents from group H10W 20/056. Groups H10W 20/056 and H10W 20/0595 should be

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			considered in order to perform a complete search
N	H10W 20/063		Group H10W 20/063 is impacted by reclassification into groups H10W 20/0633 and H10W 20/0636. Groups H10W 20/063, H10W 20/0633 and H10W 20/0636 should be considered in order to perform a complete search.
N	H10W 20/0633		Groups H10W 20/0633 - H10W 20/0636 are incomplete pending reclassification of documents from group H10W 20/063. Groups H10W 20/063 and H10W 20/0633 - H10W 20/0636 should be considered in order to perform a complete search.
N	H10W 20/069		Group H10W 20/069 is impacted by reclassification into groups H10W 20/0693 and H10W 20/0696. Groups H10W 20/069, H10W 20/0693 and H10W 20/0696 should be considered in order to perform a complete search.
N	H10W 20/0693		Groups H10W 20/0693 - H10W 20/0696 are incomplete pending reclassification of documents from group H10W 20/069. Groups H10W 20/069 and H10W 20/0693 - H10W 20/0696 should be considered in order to perform a complete search.
N	H10W 20/20		Group H10W 20/20 is incomplete pending reclassification of documents from group H10W 72/823. Group H10W 20/20 is also impacted by reclassification into groups H10W 20/211, H10W 20/212, H10W 20/2125, H10W 20/2128, H10W 20/213, H10W 20/2134, H10W 20/215, H10W 20/216, H10W 20/217, H10W 20/218, H10W 20/222 and H10W 20/233. All groups listed in this Warning should be considered in order to perform a complete search.
N	H10W 20/211		Groups H10W 20/211 and H10W 20/215 are incomplete pending reclassification of documents from groups H10W 20/20 and H10W 72/823. All groups listed in this Warning should be considered in order to perform a complete search.
N	H10W 20/212		Groups H10W 20/212, H10W 20/2125 and H10W 20/2128 are incomplete pending reclassification of documents from group H10W 20/20. All groups listed in this Warning should be considered in order to perform a complete search.

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N	H10W 20/213		Groups H10W 20/213 and H10W 20/2134 are incomplete pending reclassification of documents from group H10W 20/20. Groups H10W 20/20, H10W 20/213 and H10W 20/2134 should be considered in order to perform a complete search.
N	H10W 20/216		Groups H10W 20/216 - H10W 20/218 are incomplete pending reclassification of documents from group H10W 20/20. Groups H10W 20/20 and H10W 20/216 - H10W 20/218 should be considered in order to perform a complete search.
N	H10W 20/222		Group H10W 20/222 is incomplete pending reclassification of documents from groups H10W 20/20 and H10W 72/823. Groups H10W 20/20, H10W 72/823 and H10W 20/222 should be considered in order to perform a complete search.
N	H10W 20/233		Group H10W 20/233 is incomplete pending reclassification of documents from group H10W 20/20. Groups H10W 20/20 and H10W 20/233 should be considered in order to perform a complete search.
N	H10W 20/40		Group H10W 20/40 is impacted by reclassification into groups H10W 20/41, H10W 20/42, H10W 20/421, H10W 20/422, H10W 20/423, H10W 20/425, H10W 20/427, H10W 20/43, H10W 20/432, H10W 20/435, H10W 20/438, H10W 20/44, H10W 20/4403, H10W 20/4405, H10W 20/4407, H10W 20/4421, H10W 20/4424, H10W 20/4432, H10W 20/4435, H10W 20/4441, H10W 20/4446, H10W 20/4451, H10W 20/4462, H10W 20/4473, H10W 20/4484, H10W 20/45, H10W 20/455, H10W 20/46, H10W 20/47, H10W 20/48, H10W 20/481, H10W 20/482, H10W 70/60, H10W 70/611, H10W 70/614, H10W 70/616, H10W 70/62, H10W 70/63, H10W 70/635, H10W 70/641, H10W 70/644, H10W 70/65, H10W 70/652, H10W 70/6523, H10W 70/6525, H10W 70/6528, H10W 70/654, H10W 70/655, H10W 70/656, H10W 70/657, H10W 70/658, H10W 70/66, H10W 70/662, H10W 70/664, H10W 70/666, H10W 70/668, H10W 70/67, H10W 70/68, H10W 70/681, H10W 70/682, H10W 70/685, H10W 70/688, H10W 70/69, H10W

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			70/692, H10W 70/695, H10W 70/698 and H10W 72/00. All groups listed in this Warning should be considered in order to perform a complete search.
N	H10W 20/41		Groups H10W 20/41, H10W 20/423, H10W 20/427, H10W 20/43, H10W 20/432, H10W 20/435, H10W 20/438, H10W 20/44, H10W 20/4405, H10W 20/4407, H10W 20/4421, H10W 20/4424, H10W 20/4432, H10W 20/4435, H10W 20/4441, H10W 20/4446, H10W 20/4451, H10W 20/4462, H10W 20/4473 and H10W 20/4484 are incomplete pending reclassification of documents from group H10W 20/40. All groups listed in this Warning should be considered in order to perform a complete search.
N	H10W 20/42		Group H10W 20/42 is incomplete pending reclassification of documents from groups H10W 20/40 and H10W 20/482. Group H10W 20/42 is also impacted by reclassification into groups H10W 20/421 and H10W 20/422. All groups listed in this Warning should be considered in order to perform a complete search.
N	H10W 20/421		Group H10W 20/421 is incomplete pending reclassification of documents from groups H10W 20/40 and H10W 20/42. Groups H10W 20/40, H10W 20/42 and H10W 20/421 should be considered in order to perform a complete search.
N	H10W 20/422		Group H10W 20/422 is incomplete pending reclassification of documents from groups H10W 20/40 and H10W 20/42. Groups H10W 20/40, H10W 20/42 and H10W 20/422 should be considered in order to perform a complete search.
N	H10W 20/425		Group H10W 20/425 is incomplete pending reclassification of documents from group H10W 20/40. Group H10W 20/425 is also impacted by reclassification into group H10W 20/455. Groups H10W 20/40, H10W 20/425 and H10W 20/455 should be considered in order to perform a complete search.
N	H10W 20/4403		Group H10W 20/4403 is incomplete pending reclassification of documents from group H10W 20/40. Group H10W 20/4403 is also impacted by reclassification into group H10W 20/4437. Groups H10W 20/40, H10W 20/4403 and

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			H10W 20/4437 should be considered in order to perform a complete search.
N	H10W 20/4437		Group H10W 20/4437 is incomplete pending reclassification of documents from group H10W 20/4403. Groups H10W 20/4403 and H10W 20/4437 should be considered in order to perform a complete search.
N	H10W 20/45		Groups H10W 20/45, H10W 20/46, H10W 20/47 and H10W 20/48 are incomplete pending reclassification of documents from group H10W 20/40. All groups listed in this Warning should be considered in order to perform a complete search.
N	H10W 20/455		Group H10W 20/455 is incomplete pending reclassification of documents from groups H10W 20/40 and H10W 20/425. Groups H10W 20/40, H10W 20/425 and H10W 20/455 should be considered in order to perform a complete search.
N	H10W 20/481		Group H10W 20/481 is incomplete pending reclassification of documents from group H10W 20/40. Groups H10W 20/40 and H10W 20/481 should be considered in order to perform a complete search.
N	H10W 20/482		Group H10W 20/482 is incomplete pending reclassification of documents from group H10W 20/40. Groups H10W 20/40 and H10W 20/482 should be considered in order to perform a complete search.
N	H10W 40/00		Group H10W 40/00 is incomplete pending reclassification of documents from group H10W 99/00. Group H10W 40/00 is also impacted by reclassification into groups H10W 40/20 and H10W 40/50. All groups listed in this Warning should be considered in order to perform a complete search.
N	H10W 40/01		Group H10W 40/01 is incomplete pending reclassification of documents from group H10W 99/00. Groups H10W 99/00 and H10W 40/01 should be considered in order to perform a complete search.
N	H10W 40/03		Group H10W 40/03 is incomplete pending reclassification of documents from group H10W 70/02. Groups H10W 70/02 and

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			H10W 40/03 should be considered in order to perform a complete search.
N	H10W 40/033		Group H10W 40/033 is incomplete pending reclassification of documents from group H10W 70/027. Groups H10W 70/027 and H10W 40/033 should be considered in order to perform a complete search.
N	H10W 40/20		Group H10W 40/20 is incomplete pending reclassification of documents from group H10W 40/00. Groups H10W 40/00 and H10W 40/20 should be considered in order to perform a complete search.
N	H10W 40/22		Group H10W 40/22 is impacted by reclassification into groups H10W 40/226, H10W 40/228, H10W 40/231, H10W 40/233, H10W 40/235, H10W 40/237 and H10W 40/242. All groups listed in this Warning should be considered in order to perform a complete search.
N	H10W 40/226		Groups H10W 40/226 and H10W 40/228 are incomplete pending reclassification of documents from group H10W 40/22. Groups H10W 40/22, H10W 40/226 and H10W 40/228 should be considered in order to perform a complete search.
N	H10W 40/231		Groups H10W 40/231, H10W 40/233, H10W 40/235, H10W 40/237 and H10W 40/242 are incomplete pending reclassification of documents from group H10W 40/22. All groups listed in this Warning should be considered in order to perform a complete search.
N	H10W 40/50		Group H10W 40/50 is incomplete pending reclassification of documents from group H10W 40/00. Groups H10W 40/00 and H10W 40/50 should be considered in order to perform a complete search.
N	H10W 40/80		Group H10W 40/80 is incomplete pending reclassification of documents from group H10W 42/00. Groups H10W 42/00 and H10W 40/80 should be considered in order to perform a complete search.
N	H10W 42/00		Group H10W 42/00 is incomplete pending reclassification of documents from group H10W 99/00. Group H10W 42/00 is also impacted by reclassification into groups H10W 42/101, H10W 40/80 and H10W 99/00. All groups listed in this Warning should be considered in order to perform a complete search.

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N	H10W 42/101		Group H10W 42/101 is incomplete pending reclassification of documents from group H10W 42/00. Groups H10W 42/00 and H10W 42/101 should be considered in order to perform a complete search.
N	H10W 42/20		Group H10W 42/20 is impacted by reclassification into groups H10W 42/40, H10W 42/261, H10W 42/263, H10W 42/265, H10W 42/267, H10W 42/271, H10W 42/273, H10W 42/276, H10W 42/281, H10W 42/284 and H10W 42/287. All groups listed in this Warning should be considered in order to perform a complete search.
N	H10W 42/261		Groups H10W 42/261, H10W 42/263, H10W 42/265, H10W 42/267, H10W 42/271, H10W 42/273 and H10W 42/276 are incomplete pending reclassification of documents from group H10W 42/20. All groups listed in this Warning should be considered in order to perform a complete search.
N	H10W 42/281		Groups H10W 42/281, H10W 42/284 and H10W 42/287 are incomplete pending reclassification of documents from group H10W 42/20. All groups listed in this Warning should be considered in order to perform a complete search.
N	H10W 42/40		Group H10W 42/40 is incomplete pending reclassification of documents from group H10W 42/20. Groups H10W 42/20 and H10W 42/40 should be considered in order to perform a complete search.
N	H10W 70/00		Groups H10W 70/00, H10W 70/01 and H10W 70/04 are incomplete pending reclassification of documents from group H10W 99/00. All groups listed in this Warning should be considered in order to perform a complete search.
N	H10W 70/02		Group H10W 70/02 is incomplete pending reclassification of documents from group H10W 99/00. Group H10W 70/02 is also impacted by reclassification into group H10W 40/03. Groups H10W 99/00, H10W 70/02 and H10W 40/03 should be considered in order to perform a complete search.
N	H10W 70/027		Group H10W 70/027 is impacted by reclassification into group H10W 40/033. Groups H10W 70/027 and H10W 40/033

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			should be considered in order to perform a complete search.
N	H10W 70/05		Group H10W 70/05 is incomplete pending reclassification of documents from group H10W 99/00. Group H10W 70/05 is also impacted by reclassification into groups H10W 70/06, H10W 70/08, H10W 70/09, H10W 70/092, H10W 70/093, H10W 70/095, H10W 70/096, H10W 70/097 and H10W 70/098. All groups listed in this Warning should be considered in order to perform a complete search.
N	H10W 70/06		Group H10W 70/06 is incomplete pending reclassification of documents from groups H10W 70/05 and H10W 99/00. Groups H10W 70/05, H10W 99/00 and H10W 70/06 should be considered in order to perform a complete search.
N	H10W 70/08		Groups H10W 70/08 and H10W 70/09 are incomplete pending reclassification of documents from groups H10W 70/05 and H10W 99/00. All groups listed in this Warning should be considered in order to perform a complete search.
N	H10W 70/092		Groups H10W 70/092 - H10W 70/098 are incomplete pending reclassification of documents from group H10W 70/05. Groups H10W 70/05 and H10W 70/092 - H10W 70/098 should be considered in order to perform a complete search.
N	H10W 70/60		Group H10W 70/60 is incomplete pending reclassification of documents from group H10W 20/40. Group H10W 70/60 is also impacted by reclassification into groups H10W 70/611, H10W 70/614, H10W 70/616, H10W 70/618, H10W 70/62, H10W 70/63, H10W 70/635, H10W 70/641, H10W 70/644, H10W 70/65, H10W 70/652, H10W 70/6523, H10W 70/6525, H10W 70/6528, H10W 70/654, H10W 70/655, H10W 70/656, H10W 70/6565, H10W 70/657, H10W 70/658, H10W 70/66, H10W 70/662, H10W 70/664, H10W 70/666, H10W 70/668, H10W 70/67, H10W 70/68, H10W 70/681, H10W 70/682, H10W 70/685, H10W 70/686, H10W 70/687, H10W 70/69, H10W 70/692, H10W 70/695, H10W 70/698 and H10W 70/699. All groups listed in this Warning should be considered in order to perform a complete search.

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N	H10W 70/611		Groups H10W 70/611, H10W 70/614 and H10W 70/616 are incomplete pending reclassification of documents from groups H10W 20/40 and H10W 70/60. All groups listed in this Warning should be considered in order to perform a complete search.
N	H10W 70/618		Group H10W 70/618 is incomplete pending reclassification of documents from group H10W 70/60. Groups H10W 70/60 and H10W 70/618 should be considered in order to perform a complete search.
N	H10W 70/62		Groups H10W 70/62, H10W 70/63, H10W 70/635, H10W 70/641 and H10W 70/644 are incomplete pending reclassification of documents from groups H10W 20/40 and H10W 70/60. All groups listed in this Warning should be considered in order to perform a complete search.
N	H10W 70/65		Group H10W 70/65 is incomplete pending reclassification of documents from groups H10W 20/40 and H10W 70/60. Group H10W 70/65 is also impacted by reclassification into groups H10W 70/652, H10W 70/6523, H10W 70/6525, H10W 70/6528, H10W 70/654, H10W 70/655, H10W 70/656, H10W 70/6565, H10W 70/657 and H10W 70/658. All groups listed in this Warning should be considered in order to perform a complete search.
N	H10W 70/652		Groups H10W 70/652, H10W 70/6523, H10W 70/6525 and H10W 70/6528 are incomplete pending reclassification of documents from groups H10W 20/40, H10W 70/60 and H10W 70/65. All groups listed in this Warning should be considered in order to perform a complete search.
N	H10W 70/654		Groups H10W 70/654, H10W 70/655 and H10W 70/656 are incomplete pending reclassification of documents from groups H10W 20/40, H10W 70/60 and H10W 70/65. All groups listed in this Warning should be considered in order to perform a complete search.
N	H10W 70/6565		Group H10W 70/6565 is incomplete pending reclassification of documents from groups H10W 70/60 and H10W 70/65. Groups H10W 70/60, H10W 70/65

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			and H10W 70/6565 should be considered in order to perform a complete search.
N	H10W 70/657		Groups H10W 70/657 - H10W 70/658 are incomplete pending reclassification of documents from groups H10W 20/40, H10W 70/60 and H10W 70/65. All groups listed in this Warning should be considered in order to perform a complete search.
N	H10W 70/66		Group H10W 70/66 is incomplete pending reclassification of documents from groups H10W 20/40 and H10W 70/60. Group H10W 70/66 is also impacted by reclassification into groups H10W 70/662, H10W 70/664, H10W 70/666 and H10W 70/668. All groups listed in this Warning should be considered in order to perform a complete search.
N	H10W 70/662		Groups H10W 70/662 - H10W 70/668 are incomplete pending reclassification of documents from groups H10W 20/40, H10W 70/60 and H10W 70/66. All groups listed in this Warning should be considered in order to perform a complete search.
N	H10W 70/67		Groups H10W 70/67, H10W 70/68, H10W 70/681 and H10W 70/682 are incomplete pending reclassification of documents from groups H10W 20/40 and H10W 70/60. All groups listed in this Warning should be considered in order to perform a complete search.
N	H10W 70/685		Group H10W 70/685 is incomplete pending reclassification of documents from groups H10W 20/40 and H10W 70/60. Group H10W 70/685 is also impacted by reclassification into groups H10W 70/686 and H10W 70/687. All groups listed in this Warning should be considered in order to perform a complete search.
N	H10W 70/686		Group H10W 70/686 is incomplete pending reclassification of documents from groups H10W 70/60, H10W 70/685 and H10W 70/69. All groups listed in this Warning should be considered in order to perform a complete search.
N	H10W 70/687		Group H10W 70/687 is incomplete pending reclassification of documents from groups H10W 70/60 and H10W 70/685. Groups H10W 70/60, H10W

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			70/685 and H10W 70/687 should be considered in order to perform a complete search.
N	H10W 70/688		Group H10W 70/688 is incomplete pending reclassification of documents from group H10W 20/40. Groups H10W 20/40 and H10W 70/688 should be considered in order to perform a complete search.
N	H10W 70/69		Group H10W 70/69 is incomplete pending reclassification of documents from groups H10W 20/40 and H10W 70/60. Group H10W 70/69 is also impacted by reclassification into groups H10W 70/692, H10W 70/695, H10W 70/698 and H10W 70/686. All groups listed in this Warning should be considered in order to perform a complete search
N	H10W 70/692		Groups H10W 70/692 - H10W 70/698 are incomplete pending reclassification of documents from groups H10W 20/40, H10W 70/60 and H10W 70/69. All groups listed in this Warning should be considered in order to perform a complete search.
N	H10W 70/699		Group H10W 70/699 is incomplete pending reclassification of documents from group H10W 70/60. Groups H10W 70/60 and H10W 70/699 should be considered in order to perform a complete search.
N	H10W 72/00		Group H10W 72/00 is incomplete pending reclassification of documents from groups H10W 20/40, H10W 72/07232, H10W 72/07233 and H10W 72/07236. Group H10W 72/00 is also impacted by reclassification into groups H10W 72/20, H10W 72/221, H10W 72/222, H10W 72/223, H10W 72/224, H10W 72/225, H10W 72/227, H10W 72/228, H10W 72/231, H10W 72/232, H10W 72/234, H10W 72/235, H10W 72/237, H10W 72/241, H10W 72/242, H10W 72/244, H10W 72/245, H10W 72/247, H10W 72/248, H10W 72/251, H10W 72/252, H10W 72/253, H10W 72/255, H10W 72/257, H10W 72/2524, H10W 72/2528, H10W 72/261, H10W 72/263, H10W 72/265, H10W 72/267, H10W 72/281, H10W 72/283, H10W 72/285, H10W 72/287, H10W 72/30, H10W 72/321, H10W 72/322, H10W 72/323, H10W

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			72/324, H10W 72/325, H10W 72/327, H10W 72/328, H10W 72/331, H10W 72/332, H10W 72/334, H10W 72/335, H10W 72/337, H10W 72/341, H10W 72/342, H10W 72/344, H10W 72/345, H10W 72/347, H10W 72/348, H10W 72/351, H10W 72/352, H10W 72/353, H10W 72/354, H10W 72/355, H10W 72/357, H10W 72/3524, H10W 72/3528, H10W 72/361, H10W 72/365, H10W 72/367, H10W 72/381, H10W 72/383, H10W 72/385, H10W 72/387, H10W 72/40, H10W 72/49, H10W 72/50, H10W 72/521, H10W 72/522, H10W 72/523, H10W 72/524, H10W 72/525, H10W 72/527, H10W 72/528, H10W 72/531, H10W 72/533, H10W 72/534, H10W 72/535, H10W 72/537, H10W 72/536, H10W 72/5363, H10W 72/5366, H10W 72/5368, H10W 72/541, H10W 72/543, H10W 72/547, H10W 72/5434, H10W 72/5438, H10W 72/5473, H10W 72/5475, H10W 72/5445, H10W 72/5449, H10W 72/5453, H10W 72/551, H10W 72/552, H10W 72/5522, H10W 72/5524, H10W 72/5525, H10W 72/553, H10W 72/555, H10W 72/557, H10W 72/5528, H10W 72/581, H10W 72/583, H10W 72/585, H10W 72/60, H10W 72/621, H10W 72/622, H10W 72/623, H10W 72/624, H10W 72/625, H10W 72/627, H10W 72/631, H10W 72/634, H10W 72/635, H10W 72/637, H10W 72/641, H10W 72/645, H10W 72/647, H10W 72/646, H10W 72/642, H10W 72/643, H10W 72/6478, H10W 72/651, H10W 72/652, H10W 72/653, H10W 72/6528, H10W 72/655, H10W 72/657, H10W 72/681, H10W 72/683, H10W 72/685 and H10W 72/691. All groups listed in this Warning should be considered in order to perform a complete search.
	H10W 72/01		Group H10W 72/01 is impacted by reclassification into groups H10W 72/011, H10W 72/0112, H10W 72/0113, H10W 72/0115, H10W 72/0116, H10W 72/012, H10W 72/01204, H10W 72/01208, H10W 72/01212, H10W 72/01215, H10W 72/01221, H10W 72/01223, H10W 72/01225, H10W 72/01231, H10W 72/01233, H10W 72/01235, H10W 72/01236, H10W 72/01238, H10W 72/01251, H10W 72/01253, H10W

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N			72/01255, H10W 72/01257, H10W 72/01261, H10W 72/01265, H10W 72/01271, H10W 72/013, H10W 72/01304, H10W 72/01308, H10W 72/01315, H10W 72/01321, H10W 72/01323, H10W 72/01325, H10W 72/01331, H10W 72/01333, H10W 72/01335, H10W 72/01336, H10W 72/01338, H10W 72/01351, H10W 72/01353, H10W 72/01355, H10W 72/01357, H10W 72/01359, H10W 72/01361, H10W 72/01365, H10W 72/01371, H10W 72/014, H10W 72/015, H10W 72/01504, H10W 72/01515, H10W 72/01551, H10W 72/01553, H10W 72/01561, H10W 72/01565, H10W 72/01571, H10W 72/016, H10W 72/01604, H10W 72/01615, H10W 72/01651, H10W 72/01653, H10W 72/01661, H10W 72/01665, H10W 72/01671, H10W 72/019, H10W 72/01904, H10W 72/01908, H10W 72/01921, H10W 72/01923, H10W 72/01925, H10W 72/01931, H10W 72/01933, H10W 72/01935, H10W 72/01936, H10W 72/01938, H10W 72/01951, H10W 72/01953, H10W 72/01955, H10W 72/01961, H10W 72/01971 and H10W 72/0198. All groups listed in this Warning should be considered in order to perform a complete search.
N	H10W 72/011		Groups H10W 72/011, H10W 72/0112, H10W 72/0113, H10W 72/0115 and H10W 72/0116 are incomplete pending reclassification of documents from group H10W 72/01. All groups listed in this Warning should be considered in order to perform a complete search.
N	H10W 72/012		Group H10W 72/012 is incomplete pending reclassification of documents from group H10W 72/01. Group H10W 72/012 is also impacted by reclassification into groups H10W 72/01204, H10W 72/01208, H10W 72/01212, H10W 72/01215, H10W 72/01221, H10W 72/01223, H10W 72/01225, H10W 72/01231, H10W 72/01233, H10W 72/01235, H10W 72/01236, H10W 72/01238, H10W 72/01251, H10W 72/01253, H10W 72/01255, H10W 72/01257, H10W 72/01261, H10W

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			72/01265 and H10W 72/01271. All groups listed in this Warning should be considered in order to perform a complete search.
N	H10W 72/01204		Groups H10W 72/01204 - H10W 72/01215 are incomplete pending reclassification of documents from groups H10W 72/01 and H10W 72/012. All groups listed in this Warning should be considered in order to perform a complete search.
N	H10W 72/01221		Groups H10W 72/01221, H10W 72/01223 and H10W 72/01225 are incomplete pending reclassification of documents from groups H10W 72/01 and H10W 72/012. All groups listed in this Warning should be considered in order to perform a complete search.
N	H10W 72/01231		Groups H10W 72/01231, H10W 72/01233, H10W 72/01235, H10W 72/01236 and H10W 72/01238 are incomplete pending reclassification of documents from groups H10W 72/01 and H10W 72/012. All groups listed in this Warning should be considered in order to perform a complete search.
N	H10W 72/01251		Groups H10W 72/01251, H10W 72/01253, H10W 72/01255 and H10W 72/01257 are incomplete pending reclassification of documents from groups H10W 72/01 and H10W 72/012. All groups listed in this Warning should be considered in order to perform a complete search.
N	H10W 72/01261		Groups H10W 72/01261 - H10W 72/01271 are incomplete pending reclassification of documents from groups H10W 72/01 and H10W 72/012. All groups listed in this Warning should be considered in order to perform a complete search.
N	H10W 72/013		Group H10W 72/013 is incomplete pending reclassification of documents from group H10W 72/01. Group H10W 72/013 is also impacted by reclassification into groups H10W 72/01304, H10W 72/01308, H10W 72/01315, H10W 72/01321, H10W 72/01323, H10W 72/01325, H10W 72/01331, H10W 72/01333, H10W 72/01335, H10W 72/01336, H10W 72/01338, H10W 72/01351, H10W 72/01353, H10W

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			72/01355, H10W 72/01357, H10W 72/01359, H10W 72/01361, H10W 72/01365 and H10W 72/01371. All groups listed in this Warning should be considered in order to perform a complete search.
N	H10W 72/01304		Groups H10W 72/01304 - H10W 72/01315 are incomplete pending reclassification of documents from groups H10W 72/01 and H10W 72/013. All groups listed in this Warning should be considered in order to perform a complete search.
N	H10W 72/01321		Groups H10W 72/01321, H10W 72/01323 and H10W 72/01325 are incomplete pending reclassification of documents from groups H10W 72/01 and H10W 72/013. All groups listed in this Warning should be considered in order to perform a complete search.
N	H10W 72/01331		Groups H10W 72/01331, H10W 72/01333, H10W 72/01335, H10W 72/01336 and H10W 72/01338 are incomplete pending reclassification of documents from groups H10W 72/01 and H10W 72/013. All groups listed in this Warning should be considered in order to perform a complete search.
N	H10W 72/01351		Groups H10W 72/01351, H10W 72/01353, H10W 72/01355, H10W 72/01357 and H10W 72/01359 are incomplete pending reclassification of documents from groups H10W 72/01 and H10W 72/013. All groups listed in this Warning should be considered in order to perform a complete search.
N	H10W 72/01361		Groups H10W 72/01361 - H10W 72/01371 are incomplete pending reclassification of documents from groups H10W 72/01 and H10W 72/013. All groups listed in this Warning should be considered in order to perform a complete search.
N	H10W 72/014		Group H10W 72/014 is incomplete pending reclassification of documents from groups H10W 72/01 and H10W 72/30. Groups H10W 72/01, H10W 72/30 and H10W 72/014 should be considered in order to perform a complete search.
N	H10W 72/015		Group H10W 72/015 is incomplete pending reclassification of documents

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			from group H10W 72/01. Group H10W 72/015 is also impacted by reclassification into groups H10W 72/01504, H10W 72/01515, H10W 72/01551, H10W 72/01553, H10W 72/01561, H10W 72/01565 and H10W 72/01571. All groups listed in this Warning should be considered in order to perform a complete search.
N	H10W 72/01504		Groups H10W 72/01504 - H10W 72/01571 are incomplete pending reclassification of documents from groups H10W 72/01 and H10W 72/015. All groups listed in this Warning should be considered in order to perform a complete search
N	H10W 72/016		Group H10W 72/016 is incomplete pending reclassification of documents from group H10W 72/01. Group H10W 72/016 is also impacted by reclassification into groups H10W 72/01604, H10W 72/01615, H10W 72/01651, H10W 72/01653, H10W 72/01661, H10W 72/01665 and H10W 72/01671. All groups listed in this Warning should be considered in order to perform a complete search.
N	H10W 72/01604		Groups H10W 72/01604 - H10W 72/01671 are incomplete pending reclassification of documents from groups H10W 72/01 and H10W 72/016. All groups listed in this Warning should be considered in order to perform a complete search.
N	H10W 72/019		Group H10W 72/019 is incomplete pending reclassification of documents from group H10W 72/01. Group H10W 72/019 is also impacted by reclassification into groups H10W 72/01904, H10W 72/01908, H10W 72/01921, H10W 72/01923, H10W 72/01925, H10W 72/01931, H10W 72/01933, H10W 72/01935, H10W 72/01936, H10W 72/01938, H10W 72/01951, H10W 72/01953, H10W 72/01955, H10W 72/01961 and H10W 72/01971. All groups listed in this Warning should be considered in order to perform a complete search.
N	H10W 72/01904		Groups H10W 72/01904 - H10W 72/01908 are incomplete pending reclassification of documents from groups

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			H10W 72/01 and H10W 72/019. Groups H10W 72/01, H10W 72/019 and H10W 72/01904 should be considered in order to perform a complete search.
N	H10W 72/01921		Groups H10W 72/01921, H10W 72/01923 and H10W 72/01925 are incomplete pending reclassification of documents from groups H10W 72/01 and H10W 72/019. All groups listed in this Warning should be considered in order to perform a complete search.
N	H10W 72/01931		Groups H10W 72/01931, H10W 72/01933, H10W 72/01935, H10W 72/01936 and H10W 72/01938 are incomplete pending reclassification of documents from groups H10W 72/01 and H10W 72/019. All groups listed in this Warning should be considered in order to perform a complete search.
N	H10W 72/01951		Groups H10W 72/01951, H10W 72/01953 and H10W 72/01955 are incomplete pending reclassification of documents from groups H10W 72/01 and H10W 72/019. All groups listed in this Warning should be considered in order to perform a complete search.
N	H10W 72/01961		Groups H10W 72/01961 - H10W 72/01971 are incomplete pending reclassification of documents from groups H10W 72/01 and H10W 72/019. All groups listed in this Warning should be considered in order to perform a complete search.
N	H10W 72/0198		Group H10W 72/0198 is incomplete pending reclassification of documents from group H10W 72/01. Groups H10W 72/01 and H10W 72/0198 should be considered in order to perform a complete search.
N	H10W 72/07204		Group H10W 72/07204 is impacted by reclassification into group H10W 72/07207. Groups H10W 72/07204 and H10W 72/07207 should be considered in order to perform a complete search.
N	H10W 72/07207		Group H10W 72/07207 is incomplete pending reclassification of documents from group H10W 72/07204. Groups H10W 72/07204 and H10W 72/07207 should be considered in order to perform a complete search.

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N	H10W 72/07232		Group H10W 72/07232 is impacted by reclassification into groups H10W 72/00, H10W 72/07332, H10W 72/07532, H10W 72/07632 and H10W 95/00. All groups listed in this Warning should be considered in order to perform a complete search.
N	H10W 72/07233		Group H10W 72/07233 is impacted by reclassification into groups H10W 72/00, H10W 72/07333, H10W 72/07533, H10W 72/07633 and H10W 95/00. All groups listed in this Warning should be considered in order to perform a complete search.
N	H10W 72/07236		Group H10W 72/07236 is impacted by reclassification into groups H10W 72/00, H10W 72/07336, H10W 72/07536, H10W 72/07636 and H10W 95/00. All groups listed in this Warning should be considered in order to perform a complete search.
N	H10W 72/07332		Group H10W 72/07332 is incomplete pending reclassification of documents from group H10W 72/07232. Groups H10W 72/07232 and H10W 72/07332 should be considered in order to perform a complete search.
N	H10W 72/07333		Group H10W 72/07333 is incomplete pending reclassification of documents from group H10W 72/07233. Groups H10W 72/07233 and H10W 72/07333 should be considered in order to perform a complete search.
N	H10W 72/07336		Group H10W 72/07336 is incomplete pending reclassification of documents from group H10W 72/07236. Groups H10W 72/07236 and H10W 72/07336 should be considered in order to perform a complete search.
N	H10W 72/074		Group H10W 72/074 is incomplete pending reclassification of documents from group H10W 72/30. Groups H10W 72/30 and H10W 72/074 should be considered in order to perform a complete search.
N	H10W 72/07532		Group H10W 72/07532 is incomplete pending reclassification of documents from group H10W 72/07232. Groups H10W 72/07232 and H10W 72/07532 should be considered in order to perform a complete search.

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N	H10W 72/07533		Group H10W 72/07533 is incomplete pending reclassification of documents from group H10W 72/07233. Groups H10W 72/07233 and H10W 72/07533 should be considered in order to perform a complete search.
N	H10W 72/07536		Group H10W 72/07536 is incomplete pending reclassification of documents from group H10W 72/07236. Groups H10W 72/07236 and H10W 72/07536 should be considered in order to perform a complete search.
N	H10W 72/07632		Group H10W 72/07632 is incomplete pending reclassification of documents from group H10W 72/07232. Groups H10W 72/07232 and H10W 72/07632 should be considered in order to perform a complete search.
N	H10W 72/07633		Group H10W 72/07633 is incomplete pending reclassification of documents from group H10W 72/07233. Groups H10W 72/07233 and H10W 72/07633 should be considered in order to perform a complete search.
N	H10W 72/07636		Group H10W 72/07636 is incomplete pending reclassification of documents from group H10W 72/07236. Groups H10W 72/07236 and H10W 72/07636 should be considered in order to perform a complete search.
N	H10W 72/20		Group H10W 72/20 is incomplete pending reclassification of documents from group H10W 72/00. Group H10W 72/20 is also impacted by reclassification into groups H10W 72/221, H10W 72/222, H10W 72/223, H10W 72/224, H10W 72/225, H10W 72/227, H10W 72/228, H10W 72/231, H10W 72/232, H10W 72/234, H10W 72/235, H10W 72/237, H10W 72/241, H10W 72/242, H10W 72/244, H10W 72/245, H10W 72/247, H10W 72/248, H10W 72/251, H10W 72/252, H10W 72/253, H10W 72/255, H10W 72/257, H10W 72/2524, H10W 72/2528, H10W 72/261, H10W 72/263, H10W 72/265, H10W 72/267, H10W 72/281, H10W 72/283, H10W 72/285, H10W 72/287, H10W 72/60, H10W 72/621, H10W 72/622, H10W 72/623, H10W 72/624, H10W 72/625, H10W 72/627, H10W 72/631, H10W 72/634, H10W 72/635, H10W 72/637, H10W 72/641,

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			H10W 72/645, H10W 72/647, H10W 72/642, H10W 72/643, H10W 72/646, H10W 72/6478, H10W 72/651, H10W 72/652, H10W 72/653, H10W 72/6528, H10W 72/655, H10W 72/657, H10W 72/681, H10W 72/683, H10W 72/685 and H10W 72/691. All groups listed in this Warning should be considered in order to perform a complete search.
N	H10W 72/221		Groups H10W 72/221, H10W 72/222, H10W 72/223, H10W 72/224, H10W 72/225, H10W 72/227 and H10W 72/228 are incomplete pending reclassification of documents from groups H10W 72/00 and H10W 72/20. All groups listed in this Warning should be considered in order to perform a complete search.
N	H10W 72/231		Groups H10W 72/231, H10W 72/232, H10W 72/234, H10W 72/235 and H10W 72/237 are incomplete pending reclassification of documents from groups H10W 72/00 and H10W 72/20. All groups listed in this Warning should be considered in order to perform a complete search.
N	H10W 72/241		Groups H10W 72/241, H10W 72/242, H10W 72/244, H10W 72/245, H10W 72/247 and H10W 72/248 are incomplete pending reclassification of documents from groups H10W 72/00 and H10W 72/20. All groups listed in this Warning should be considered in order to perform a complete search.
N	H10W 72/251		Groups H10W 72/251, H10W 72/252, H10W 72/2524, H10W 72/2528, H10W 72/253, H10W 72/255 and H10W 72/257 are incomplete pending reclassification of documents from groups H10W 72/00 and H10W 72/20. All groups listed in this Warning should be considered in order to perform a complete search.
N	H10W 72/261		Groups H10W 72/261, H10W 72/263, H10W 72/265 and H10W 72/267 are incomplete pending reclassification of documents from groups H10W 72/00 and H10W 72/20. All groups listed in this Warning should be considered in order to perform a complete search.
N	H10W 72/281		Groups H10W 72/281, H10W 72/283, H10W 72/285 and H10W 72/287 are incomplete pending reclassification of documents from groups H10W 72/00 and

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			H10W 72/20. All groups listed in this Warning should be considered in order to perform a complete search.
N	H10W 72/30		Group H10W 72/30 is incomplete pending reclassification of documents from group H10W 72/00. Group H10W 72/30 is also impacted by reclassification into groups H10W 72/014, H10W 72/074, H10W 72/321, H10W 72/322, H10W 72/323, H10W 72/324, H10W 72/325, H10W 72/327, H10W 72/328, H10W 72/331, H10W 72/332, H10W 72/334, H10W 72/335, H10W 72/337, H10W 72/341, H10W 72/342, H10W 72/344, H10W 72/345, H10W 72/347, H10W 72/348, H10W 72/351, H10W 72/352, H10W 72/353, H10W 72/354, H10W 72/355, H10W 72/357, H10W 72/3524, H10W 72/3528, H10W 72/361, H10W 72/365, H10W 72/367, H10W 72/381, H10W 72/383, H10W 72/385, H10W 72/387, H10W 72/40 and H10W 72/49. All groups listed in this Warning should be considered in order to perform a complete search.
N	H10W 72/321		Groups H10W 72/321, H10W 72/322, H10W 72/323, H10W 72/324, H10W 72/325, H10W 72/327 and H10W 72/328 are incomplete pending reclassification of documents from groups H10W 72/00 and H10W 72/30. All groups listed in this Warning should be considered in order to perform a complete search.
N	H10W 72/331		Groups H10W 72/331, H10W 72/332, H10W 72/334, H10W 72/335 and H10W 72/337 are incomplete pending reclassification of documents from groups H10W 72/00 and H10W 72/30. All groups listed in this Warning should be considered in order to perform a complete search.
N	H10W 72/341		Groups H10W 72/341, H10W 72/342, H10W 72/344, H10W 72/345, H10W 72/347 and H10W 72/348 are incomplete pending reclassification of documents from groups H10W 72/00 and H10W 72/30. All groups listed in this Warning should be considered in order to perform a complete search.
N	H10W 72/351		Groups H10W 72/351, H10W 72/352, H10W 72/3524, H10W 72/3528, H10W 72/353, H10W 72/354, H10W 72/355 and

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			H10W 72/357 are incomplete pending reclassification of documents from groups H10W 72/00 and H10W 72/30. All groups listed in this Warning should be considered in order to perform a complete search.
N	H10W 72/361		Groups H10W 72/361, H10W 72/365 and H10W 72/367 are incomplete pending reclassification of documents from groups H10W 72/00 and H10W 72/30. All groups listed in this Warning should be considered in order to perform a complete search.
N	H10W 72/381		Groups H10W 72/381, H10W 72/383, H10W 72/385 and H10W 72/387 are incomplete pending reclassification of documents from groups H10W 72/00 and H10W 72/30. All groups listed in this Warning should be considered in order to perform a complete search.
N	H10W 72/40		Groups H10W 72/40 and H10W 72/49 are incomplete pending reclassification of documents from groups H10W 72/00 and H10W 72/30. All groups listed in this Warning should be considered in order to perform a complete search.
N	H10W 72/50		Group H10W 72/50 is incomplete pending reclassification of documents from group H10W 72/00. Group H10W 72/50 is also impacted by reclassification into groups H10W 72/521, H10W 72/522, H10W 72/523, H10W 72/524, H10W 72/525, H10W 72/527, H10W 72/528, H10W 72/531, H10W 72/533, H10W 72/534, H10W 72/535, H10W 72/537, H10W 72/536, H10W 72/5363, H10W 72/5366, H10W 72/5368, H10W 72/541, H10W 72/543, H10W 72/547, H10W 72/5434, H10W 72/5438, H10W 72/5473, H10W 72/5475, H10W 72/5445, H10W 72/5449, H10W 72/5453, H10W 72/551, H10W 72/552, H10W 72/5522, H10W 72/5524, H10W 72/5525, H10W 72/553, H10W 72/555, H10W 72/557, H10W 72/5528, H10W 72/581, H10W 72/583 and H10W 72/585. All groups listed in this Warning should be considered in order to perform a complete search.
N	H10W 72/521		Groups H10W 72/521, H10W 72/522, H10W 72/523, H10W 72/524, H10W 72/525, H10W 72/527 and H10W 72/528 are incomplete pending reclassification of

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			documents from groups H10W 72/00 and H10W 72/50. All groups listed in this Warning should be considered in order to perform a complete search.
N	H10W 72/531		Groups H10W 72/531, H10W 72/533, H10W 72/534, H10W 72/535, H10W 72/536, H10W 72/5363, H10W 72/5366, H10W 72/5368 and H10W 72/537 are incomplete pending reclassification of documents from groups H10W 72/00 and H10W 72/50. All groups listed in this Warning should be considered in order to perform a complete search.
N	H10W 72/541		Groups H10W 72/541, H10W 72/543, H10W 72/5434, H10W 72/5438, H10W 72/5445, H10W 72/5449, H10W 72/5453, H10W 72/547, H10W 72/5473 and H10W 72/5475 are incomplete pending reclassification of documents from groups H10W 72/00 and H10W 72/50. All groups listed in this Warning should be considered in order to perform a complete search.
N	H10W 72/551		Groups H10W 72/551, H10W 72/552, H10W 72/5522, H10W 72/5524, H10W 72/5525, H10W 72/5528, H10W 72/553, H10W 72/555 and H10W 72/557 are incomplete pending reclassification of documents from groups H10W 72/00 and H10W 72/50. All groups listed in this Warning should be considered in order to perform a complete search.
N	H10W 72/581		Groups H10W 72/581, H10W 72/583 and H10W 72/585 are incomplete pending reclassification of documents from groups H10W 72/00 and H10W 72/50. All groups listed in this Warning should be considered in order to perform a complete search.
N	H10W 72/60		Group H10W 72/60 is incomplete pending reclassification of documents from groups H10W 72/00 and H10W 72/20. Group H10W 72/60 is also impacted by reclassification into groups H10W 72/621, H10W 72/622, H10W 72/623, H10W 72/624, H10W 72/625, H10W 72/627, H10W 72/631, H10W 72/634, H10W 72/635, H10W 72/637, H10W 72/641, H10W 72/645, H10W 72/647, H10W 72/646, H10W 72/642, H10W 72/643, H10W 72/6478, H10W 72/651, H10W 72/652, H10W 72/653, H10W 72/6528,

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			H10W 72/655, H10W 72/657, H10W 72/681, H10W 72/683, H10W 72/685 and H10W 72/701. All groups listed in this Warning should be considered in order to perform a complete search.
N	H10W 72/621		Groups H10W 72/621, H10W 72/622, H10W 72/623, H10W 72/624, H10W 72/625 and H10W 72/627 are incomplete pending reclassification of documents from groups H10W 72/00, H10W 72/20 and H10W 72/60. All groups listed in this Warning should be considered in order to perform a complete search.
N	H10W 72/631		Groups H10W 72/631, H10W 72/634, H10W 72/635 and H10W 72/637 are incomplete pending reclassification of documents from groups H10W 72/00, H10W 72/20 and H10W 72/60. All groups listed in this Warning should be considered in order to perform a complete search.
N	H10W 72/641		Groups H10W 72/641, H10W 72/642, H10W 72/643, H10W 72/645, H10W 72/646, H10W 72/647 and H10W 72/6478 are incomplete pending reclassification of documents from groups H10W 72/00, H10W 72/20 and H10W 72/60. All groups listed in this Warning should be considered in order to perform a complete search.
N	H10W 72/651		Groups H10W 72/651, H10W 72/652, H10W 72/6528, H10W 72/653, H10W 72/655 and H10W 72/657 are incomplete pending reclassification of documents from groups H10W 72/00, H10W 72/20 and H10W 72/60. All groups listed in this Warning should be considered in order to perform a complete search.
N	H10W 72/681		Groups H10W 72/681, H10W 72/683 and H10W 72/685 are incomplete pending reclassification of documents from groups H10W 72/00, H10W 72/20 and H10W 72/60. All groups listed in this Warning should be considered in order to perform a complete search.
N	H10W 72/691		Group H10W 72/691 is incomplete pending reclassification of documents from groups H10W 72/00 and H10W 72/20. Groups H10W 72/00, H10W 72/20 and H10W 72/691 should be considered in order to perform a complete search.

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N	H10W 72/701		Group H10W 72/701 is incomplete pending reclassification of documents from group H10W 72/60. Groups H10W 72/60 and H10W 72/701 should be considered in order to perform a complete search.
N	H10W 72/801		Group H10W 72/801 is impacted by reclassification into group H10W 72/812. Groups H10W 72/801 and H10W 72/812 should be considered in order to perform a complete search.
N	H10W 72/812		Group H10W 72/812 is incomplete pending reclassification of documents from group H10W 72/801. Groups H10W 72/801 and H10W 72/812 should be considered in order to perform a complete search.
N	H10W 72/823		Group H10W 72/823 is impacted by reclassification into groups H10W 20/20, H10W 20/211, H10W 20/215, H10W 20/222, H10W 76/132, H10W 76/134, H10W 76/153, H10W 76/157 and H10W 76/165. All groups listed in this Warning should be considered in order to perform a complete search.
N	H10W 72/90		Group H10W 72/90 is impacted by reclassification into groups H10W 72/921, H10W 72/922, H10W 72/9223, H10W 72/9226, H10W 72/923, H10W 72/9232, H10W 72/924, H10W 72/925, H10W 72/926, H10W 72/927, H10W 72/931, H10W 72/932, H10W 72/934, H10W 72/936, H10W 72/941, H10W 72/9413, H10W 72/9415, H10W 72/942, H10W 72/944, H10W 72/9445, H10W 72/951, H10W 72/952, H10W 72/953, H10W 72/957, H10W 72/9524, H10W 72/9528, H10W 72/961, H10W 72/963, H10W 72/965, H10W 72/967, H10W 72/981, H10W 72/983, H10W 72/985 and H10W 72/987. All groups listed in this Warning should be considered in order to perform a complete search.
N	H10W 72/921		Groups H10W 72/921, H10W 72/922, H10W 72/9223, H10W 72/9226, H10W 72/923, H10W 72/9232, H10W 72/924, H10W 72/925, H10W 72/926 and H10W 72/927 are incomplete pending reclassification of documents from group H10W 72/90. All groups listed in this Warning should be considered in order to perform a complete search.

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N	H10W 72/931		Groups H10W 72/931, H10W 72/932, H10W 72/934 and H10W 72/936 are incomplete pending reclassification of documents from group H10W 72/90. All groups listed in this Warning should be considered in order to perform a complete search.
N	H10W 72/941		Groups H10W 72/941, H10W 72/9413, H10W 72/9415, H10W 72/942, H10W 72/944 and H10W 72/9445 are incomplete pending reclassification of documents from group H10W 72/90. All groups listed in this Warning should be considered in order to perform a complete search.
N	H10W 72/951		Groups H10W 72/951, H10W 72/952, H10W 72/9524, H10W 72/9528, H10W 72/953 and H10W 72/957 are incomplete pending reclassification of documents from group H10W 72/90. All groups listed in this Warning should be considered in order to perform a complete search.
N	H10W 72/961		Groups H10W 72/961, H10W 72/963, H10W 72/965 and H10W 72/967 are incomplete pending reclassification of documents from group H10W 72/90. All groups listed in this Warning should be considered in order to perform a complete search.
N	H10W 72/981		Groups H10W 72/981, H10W 72/983, H10W 72/985 and H10W 72/987 are incomplete pending reclassification of documents from group H10W 72/90. All groups listed in this Warning should be considered in order to perform a complete search.
N	H10W 74/01		Group H10W 74/01 is incomplete pending reclassification of documents from group H10W 99/00. Groups H10W 99/00 and H10W 74/01 should be considered in order to perform a complete search.
N	H10W 74/10		Group H10W 74/10 is impacted by reclassification into group H10W 74/15. Groups H10W 74/10 and H10W 74/15 should be considered in order to perform a complete search.
N	H10W 74/15		Group H10W 74/15 is incomplete pending reclassification of documents from group H10W 74/10. Groups H10W 74/10 and H10W 74/15 should be considered in order to perform a complete search.

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N	H10W 76/01		Group H10W 76/01 is incomplete pending reclassification of documents from group H10W 99/00. Groups H10W 99/00 and H10W 76/01 should be considered in order to perform a complete search.
N	H10W 76/132		Groups H10W 76/132 - H10W 76/165 are incomplete pending reclassification of documents from group H10W 72/823. All groups listed in this Warning should be considered in order to perform a complete search.
N	H10W 76/60		Group H10W 76/60 is impacted by reclassification into groups H10W 76/63 and H10W 76/67. Groups H10W 76/60, H10W 76/63 and H10W 76/67 should be considered in order to perform a complete search.
N	H10W 76/63		Groups H10W 76/63 - H10W 76/67 are incomplete pending reclassification of documents from group H10W 76/60. All groups listed in this Warning should be considered in order to perform a complete search.
N	H10W 90/00		Group H10W 90/00 is impacted by reclassification into groups H10B 80/00, H10D 80/00, H10D 80/20, H10D 80/211, H10D 80/213, H10D 80/215, H10D 80/231, H10D 80/251, H10D 80/30, H10F 39/90, H10F 39/95, H10H 29/20, H10H 29/24, H10H 29/30, H10H 29/32, H10H 29/34, H10H 29/345, H10H 29/352, H10H 29/362, H10H 29/37, H10H 29/39, H10H 29/41, H10H 29/45, H10H 29/49, H10K 19/00, H10K 19/10, H10K 19/20, H10K 19/201, H10K 19/202, H10K 19/80, H10K 19/901, H10K 39/601, H10K 39/621, H10K 59/90, H10K 59/95, H10K 65/00, H10W 90/10, H10W 90/15, H10W 90/155, H10W 90/20, H10W 90/22, H10W 90/231, H10W 90/24, H10W 90/26, H10W 90/271, H10W 90/275, H10W 90/28, H10W 90/284, H10W 90/288, H10W 90/291, H10W 90/293, H10W 90/295, H10W 90/701, H10W 90/721, H10W 90/722, H10W 90/723, H10W 90/724, H10W 90/725, H10W 90/726, H10W 90/727, H10W 90/728, H10W 90/729, H10W 90/731, H10W 90/732, H10W 90/733, H10W 90/734, H10W 90/735, H10W 90/736, H10W 90/737, H10W 90/738, H10W 90/739, H10W 90/751, H10W 90/752,

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			H10W 90/753, H10W 90/754, H10W 90/755, H10W 90/756, H10W 90/757, H10W 90/758, H10W 90/759, H10W 90/761, H10W 90/762, H10W 90/763, H10W 90/764, H10W 90/765, H10W 90/766, H10W 90/767, H10W 90/768, H10W 90/769, H10W 90/791, H10W 90/792, H10W 90/794, H10W 90/796, H10W 90/798 and H10W 90/811. All groups listed in this Warning should be considered in order to perform a complete search.
N	H10W 90/10		Groups H10W 90/10, H10W 90/15 and H10W 90/155 are incomplete pending reclassification of documents from group H10W 90/00. All groups listed in this Warning should be considered in order to perform a complete search.
N	H10W 90/20		Groups H10W 90/20, H10W 90/22, H10W 90/231, H10W 90/24, H10W 90/26, H10W 90/271, H10W 90/275, H10W 90/28, H10W 90/284, H10W 90/288, H10W 90/291, H10W 90/293 and H10W 90/295 are incomplete pending reclassification of documents from group H10W 90/00. All groups listed in this Warning should be considered in order to perform a complete search.
N	H10W 90/701		Group H10W 90/701 is incomplete pending reclassification of documents from group H10W 90/00. Group H10W 90/701 is also impacted by reclassification into groups H10W 90/724, H10W 90/725, H10W 90/7295, H10W 90/754, H10W 90/755, H10W 90/764 and H10W 90/765. All groups listed in this Warning should be considered in order to perform a complete search.
N	H10W 90/721		Groups H10W 90/721, H10W 90/722, H10W 90/723, H10W 90/727, H10W 90/728 and H10W 90/729 are incomplete pending reclassification of documents from group H10W 90/00. All groups listed in this Warning should be considered in order to perform a complete search.
N	H10W 90/724		Group H10W 90/724 is incomplete pending reclassification of documents from groups H10W 90/00 and H10W 90/701. Group H10W 90/724 is also impacted by reclassification into group H10W 90/726. All groups listed in this

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			Warning should be considered in order to perform a complete search.
N	H10W 90/725		Group H10W 90/725 is incomplete pending reclassification of documents from groups H10W 90/00 and H10W 90/701. Groups H10W 90/00, H10W 90/701 and H10W 90/725 should be considered in order to perform a complete search.
N	H10W 90/726		Group H10W 90/726 is incomplete pending reclassification of documents from groups H10W 90/00 and H10W 90/724. Groups H10W 90/00, H10W 90/724 and H10W 90/726 should be considered in order to perform a complete search.
N	H10W 90/7295		Group H10W 90/7295 is incomplete pending reclassification of documents from group H10W 90/701. Groups H10W 90/701 and H10W 90/7295 should be considered in order to perform a complete search.
N	H10W 90/731		Groups H10W 90/731, H10W 90/732, H10W 90/733, H10W 90/734, H10W 90/735, H10W 90/736, H10W 90/737, H10W 90/738 and H10W 90/739 are incomplete pending reclassification of documents from group H10W 90/00. All groups listed in this Warning should be considered in order to perform a complete search.
N	H10W 90/751		Groups H10W 90/751, H10W 90/752, H10W 90/753, H10W 90/757, H10W 90/758 and H10W 90/759 are incomplete pending reclassification of documents from group H10W 90/00. All groups listed in this Warning should be considered in order to perform a complete search.
N	H10W 90/754		Group H10W 90/754 is incomplete pending reclassification of documents from groups H10W 90/00 and H10W 90/701. Group H10W 90/754 is also impacted by reclassification into group H10W 90/756. All groups listed in this Warning should be considered in order to perform a complete search.
N	H10W 90/755		Group H10W 90/755 is incomplete pending reclassification of documents from groups H10W 90/00 and H10W 90/701. Groups H10W 90/00, H10W 90/701 and H10W 90/755 should be

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			considered in order to perform a complete search.
N	H10W 90/756		Group H10W 90/756 is incomplete pending reclassification of documents from groups H10W 90/00 and H10W 90/754. Groups H10W 90/00, H10W 90/754 and H10W 90/756 should be considered in order to perform a complete search.
N	H10W 90/761		Groups H10W 90/761, H10W 90/762, H10W 90/763, H10W 90/766, H10W 90/767, H10W 90/768 and H10W 90/769 are incomplete pending reclassification of documents from group H10W 90/00. All groups listed in this Warning should be considered in order to perform a complete search.
N	H10W 90/764		Group H10W 90/764 is incomplete pending reclassification of documents from groups H10W 90/00 and H10W 90/701. Groups H10W 90/00, H10W 90/701 and H10W 90/764 should be considered in order to perform a complete search.
N	H10W 90/765		Group H10W 90/765 is incomplete pending reclassification of documents from groups H10W 90/00 and H10W 90/701. Groups H10W 90/00, H10W 90/701 and H10W 90/765 should be considered in order to perform a complete search.
N	H10W 90/791		Groups H10W 90/791, H10W 90/792, H10W 90/794, H10W 90/796 and H10W 90/798 are incomplete pending reclassification of documents from group H10W 90/00. All groups listed in this Warning should be considered in order to perform a complete search.
N	H10W 90/811		Group H10W 90/811 is incomplete pending reclassification of documents from group H10W 90/00. Groups H10W 90/00 and H10W 90/811 should be considered in order to perform a complete search.
N	H10W 95/00		Group H10W 95/00 is incomplete pending reclassification of documents from groups H10W 72/07232, H10W 72/07233, H10W 72/07236 and H10W 99/00. All groups listed in this Warning should be considered in order to perform a complete search.

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N	H10W 99/00		Group H10W 99/00 is incomplete pending reclassification of documents from group H10W 42/00. Group H10W 99/00 is also impacted by reclassification into groups H10W 40/00, H10W 40/01, H10W 42/00, H10W 70/00, H10W 70/01, H10W 70/02, H10W 70/04, H10W 70/05, H10W 70/06, H10W 70/08, H10W 70/09, H10W 74/01, H10W 76/01 and H10W 95/00. All groups listed in this Warning should be considered in order to perform a complete search.

*N = new warning, M = modified warning, D = deleted warning

NOTE: The "Location" column only requires the symbol PRIOR to the location of the warning. No further directions such as "before" or "after" are required.

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C. New, Modified or Deleted Note(s)**SUBCLASS H01L - SEMICONDUCTOR DEVICES NOT COVERED BY CLASS H10**

<u>Type*</u>	<u>Location</u>	<u>Old Note</u>	<u>New/Modified Note</u>
D	H01L 21/48	{In this group, the expression "treatment" covers also the removal of leads from parts.}	
D	H01L 21/50	{Arrangements for connecting or disconnecting semiconductor or other solid state bodies, or methods related thereto, other than those arrangements or methods covered by the following subgroups, are covered by H01L 24/00.}	
D	H01L 21/768	{Groups H01L 21/768 - H01L 21/7689 cover multi-step processes for manufacturing interconnections. Information peculiar to single-step processes should also be classified in the corresponding group, e.g. cleaning H01L 21/02041 etching H01L 21/311, H01L 21/3213 masking H01L 21/027, H01L 21/033, H01L 21/31144, H01L 21/32139 planarizing H01L 21/3105, H01L 21/321.}	
D	H01L 21/76838	{When the interconnect is also used as the conductor part of a conductor insulator semiconductor electrode (gate level interconnections), documents are classified in the relevant electrode manufacture groups, e.g. H01L 21/28026}.	
D	H01L 23/00	This group does not cover: details of semiconductor bodies or of electrodes of devices provided for in subclass H10D, which details are covered by that group; details peculiar to devices provided for in a single subclass of subclasses H10F, H10H, H10K or H10N, which details are covered by those places.	
D	H01L 23/18	Group H01L 23/26 takes precedence over groups H01L 23/20 - H01L 23/24	
D	H01L 23/48	{Arrangements for connecting or disconnecting semiconductor or other solid state bodies, or methods related thereto, other than those arrangements or methods covered by the following subgroups, are covered by H01L 24/00.}	
D	H01L 23/544	{When classifying in group H01L 23/544, details are to be further indexed by using the	

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		indexing codes chosen from H01L 2223/544 and subgroups.}	
D	H01L 23/66	{When classifying in group H01L 23/66, details are to be further indexed by using the indexing codes chosen from H01L 2223/66 and subgroups. }	
D	H01L 24/00	1. This group does not cover: details of semiconductor bodies or of electrodes of devices provided for in subclass H10D, which details are covered by that group; details peculiar to devices provided for in a single subclass of subclasses H10F, H10H, H10K or H10N, which details are covered by those places; printed circuits, which are covered by groups H05K 1/00 - H05K 1/189; apparatus or manufacturing processes for printed circuits, which are covered by groups H05K 3/00 - H05K 3/4685; manufacture or treatment of parts, which are covered by group H01L 21/48 and subgroups except H01L 21/4885 - H01L 21/4896; assemblies of semiconductor devices, which are covered by groups H01L 21/50 - H01L 21/568; applying interconnections to be used for carrying current between separate components within a device, which is covered by group H01L 21/768 and subgroups; containers or seals, which are covered by groups H01L 23/02 - H01L 23/10; mountings, which are covered by groups H01L 23/12 - H01L 23/15 and subgroups; arrangements for cooling, heating, ventilating or temperature compensation, which are covered by groups H01L 23/34 - H01L 23/4735; arrangements for conducting electric current, which are covered by groups H01L 23/48 - H01L 23/50, and by groups H01L 23/52 - H01L 23/5389; structural electrical arrangements, which are covered by groups H01L 23/58 - H01L 23/66; assemblies of semiconductor or other solid state devices, which are covered by groups H01L 25/00 - H01L 25/18. 2. In this group the following indexing codes are used : H01L 24/00, H01L 2224/00, H01L 2924/00, and subgroups thereof	
D	H01L 25/00	{Due to the ongoing developments in class H10 and related subclasses, the information displayed in notes, references and definitions of this main group and indents may not be entirely accurate. For each specific subject matter referred to in this main group and indents, users are invited to consult the	

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		relevant place in class H10 and to consider the class H10 information as correct, in case of conflict}	
D	H01L 25/065	{Group H01L 25/0652 takes precedence over groups H01L 25/0655 and H01L 25/0657.}	
D	H01L 25/07	{Group H01L 25/071 takes precedence over groups H01L 25/072 - H01L 25/074.}	
D	H01L 25/105	{When classifying in group H01L 25/105, details of the assemblies are to be further indexed by using the indexing codes chosen from H01L 2225/1005 and subgroups.}	
D	H01L 25/11	{Group H01L 25/112 takes precedence over groups H01L 25/115 and H01L 25/117.}	
D	H01L 2924/0001	Codes H01L 2924/0001 - H01L 2924/0002 are used to describe the status of reclassification; they do not relate to technical features as such	

SUBCLASS H10D - INORGANIC ELECTRIC SEMICONDUCTORS

Type*	Location	Old Note	New/Modified Note
M	H10D	1. This subclass <u>covers</u> electric semiconductor devices having inorganic semiconductor bodies. This includes the following kind of devices: • inorganic semiconductor devices specially adapted for rectifying, amplifying, oscillating or switching, e.g. transistors or diodes; • individual inorganic resistors or capacitors having potential barriers; • individual resistors, capacitors or inductors having no potential barriers, and specially adapted for integration with other semiconductor components; • semiconductor bodies, or regions thereof, of devices covered by this subclass; • electrodes of devices covered by this subclass; • integrated devices, e.g. CMOS integrated devices; • processes or apparatus specially adapted for the manufacture or treatment of such devices.	1. This subclass <u>covers</u> electric semiconductor devices having inorganic semiconductor bodies. This includes the following kind of devices: • inorganic semiconductor devices specially adapted for rectifying, amplifying, oscillating or switching, e.g. transistors or diodes; • individual inorganic resistors or capacitors having potential barriers; • individual resistors, capacitors or inductors having no potential barriers, and specially adapted for integration with other semiconductor components; • semiconductor bodies, or regions thereof, of devices covered by this subclass; • electrodes of devices covered by this subclass; • integrated devices, e.g. CMOS integrated devices; • processes or apparatus specially adapted for the manufacture or treatment of such devices.

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		2.This subclass <u>does not cover</u>: • electronic memory devices, which are covered by subclass H10B; • semiconductor devices sensitive to infrared radiation, light, electromagnetic radiation of shorter wavelength or corpuscular radiation, which are covered by subclass H10F; • light-emitting semiconductor devices having at least one potential barrier, which are covered by subclass H10H; • thermoelectric, thermomagnetic, piezoelectric, electrostrictive, magnetostrictive, magnetic-effect, superconducting or other electric solid-state devices, which are covered by subclass H10N; • constructional details other than semiconductor bodies or electrodes, which are covered by group H01L 23/00. 3.In this subclass, the periodic system used is the I to VIII group system indicated in the Periodic Table under Note (3) of section C.	2.This subclass <u>does not cover</u>: • electronic memory devices, which are covered by subclass H10B; • semiconductor devices sensitive to infrared radiation, light, electromagnetic radiation of shorter wavelength or corpuscular radiation, which are covered by subclass H10F; • light-emitting semiconductor devices having at least one potential barrier, which are covered by subclass H10H; • thermoelectric, thermomagnetic, piezoelectric, electrostrictive, magnetostrictive, magnetic-effect, superconducting or other electric solid-state devices, which are covered by subclass H10N; • constructional details other than semiconductor bodies or electrodes, which are covered by subclass H10W. 3. In this subclass, the periodic system used is the I to VIII group system indicated in the Periodic Table under Note (3) of section C.

SUBCLASS H10W - GENERIC PACKAGES, INTERCONNECTIONS, CONNECTORS OR OTHER CONSTRUCTIONAL DETAILS OF DEVICES COVERED BY CLASS H10

<u>Type*</u>	<u>Location</u>	<u>Old Note</u>	<u>New/Modified Note</u>
N	H10W		{1.} This subclass covers: a. packages of devices and parts of such packages; b. interconnections of devices in chips, wafers, substrates or packages; c. connectors of devices in packages; d. other constructional details of devices in chips, wafers, substrates or packages, e.g. isolation regions between components of integrated devices; e. detachable holders for supporting packaged chips in operation; f. the manufacture or treatment of aspects (a)-(e); when aspects (a)-(e) are (1) applicable to devices covered by subclass H10B; (2) applicable to devices covered by subclass H10D, except for semiconductor bodies or

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			electrodes thereof, which are covered by subgroups H10D 62/00 or H10D 64/00; or (3) generically applicable to devices covered by subclasses H10B, H10D, H10F, H10H, H10K or H10N. {2. In this subclass, the periodic system used is the I to VIII group system indicated in the Periodic Table under Note (3) of section C.}
N	H10W20/00		1. This group covers: • interconnections in chips; • interconnections in or on wafers; • interconnections in or on substrates. 2. This group does not cover interconnections in packages, such as in or on package substrates, which are covered by subgroups H10W 70/00 or H10W 72/00.
N	H10W 46/00		This group covers marks in or on chips, wafers, substrates or packages.
N	H10W 72/00		In this group, bond pads in general, i.e. where the nature of a related connector is unspecified or generic to multiple types of connectors, are classified in group H10W 72/90. Bond pads specially adapted for a specific type of connector are classified in the group covering the connector type. For example, bond pads specially adapted for wire connectors are classified in group H10W 72/59.
N	H10W 76/42		In this group, the phase of the fillings is determined at the operating temperature of the device.
N	H10W 80/00		This group covers direct bonding of: • chips, e.g. chip-to-chip; • wafers having devices and interconnections therein or thereon, e.g. wafer-to-wafer; • substrates having devices and interconnections therein or thereon; combinations thereof, e.g. chip-to-wafer.
N	H10W 90/00		This group covers: • the relative positions of multiple chips within a single package, e.g. adjacent chips in a single encapsulation; • the relative positions of multiple chips within multiple packages, e.g. one encapsulated chip on another encapsulated chip in a "package-on-package" configuration

*N = new note, M = modified note, D = deleted note

NOTE: The "Location" column only requires the symbol PRIOR to the location of the note. No further directions such as "before" or "after" are required.

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D. New, Modified or Deleted Guidance Heading(s)**SUBCLASS H10W - GENERIC PACKAGES, INTERCONNECTIONS, CONNECTORS OR OTHER CONSTRUCTIONAL DETAILS OF DEVICES COVERED BY CLASS H10**

<u>Type*</u>	<u>Location</u>	<u>Old Guidance Heading</u>	<u>New/Modified Guidance Heading</u>
N	H10W 10/00 - H10W 29/00		Constructional details of integrated devices in chips, wafers or substrates
N	H10W 40/00 - H10W 46/00		Constructional details related to chips, wafers, substrates or packages
N	H10W 70/00 - H10W 99/00		Aspects of packages

*N = new guidance heading, M = modified guidance heading, D = deleted guidance heading

NOTES:

- The “Location” column requires the symbol AFTER the guidance heading location. No further directions such as “before” or “after” are required.
- In cases where there may be confusion as to whether a new group falls within the scope of a guidance heading, indicate the guidance heading and whether the group does or does not go with the guidance heading. This can be included in the “Location” column. For example, the guidance heading “Compounds containing carbon together with sulfur, selenium or tellurium with or without hydrogen, halogens, oxygen or nitrogen” encompasses groups C07C 301/00-395/00 only. If a new group C07C 398/00 is proposed and is included in the guidance heading scope, indicate this in the “Location” column as follows: 398/00 to be included under the guidance heading: “Compounds containing carbon together with sulfur, selenium or tellurium with or without hydrogen, halogens, oxygen or nitrogen.”

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2. B. DEFINITIONS QUICK FIX

Symbol	Location of change (e.g., section title)	Existing reference symbol or text	Action; New symbol; New text
H01L21/48			Delete entire definition
H01L21/50			Delete entire definition
H01L21/71			Delete entire definition
H01L21/74			Delete entire definition
H01L21/743			Delete entire definition
H01L21/76			Delete entire definition
H01L21/762			Delete entire definition
H01L21/76224			Delete entire definition
H01L21/768			Delete entire definition
H01L21/76804			Delete entire definition
H01L21/76805			Delete entire definition
H01L21/76808			Delete entire definition
H01L21/7681			Delete entire definition
H01L21/76811			Delete entire definition
H01L21/76813			Delete entire definition
H01L21/76814			Delete entire definition
H01L21/76816			Delete entire definition
H01L21/76817			Delete entire definition
H01L21/76819			Delete entire definition
H01L21/76822			Delete entire definition
H01L21/76823			Delete entire definition
H01L21/76825			Delete entire definition
H01L21/76826			Delete entire definition
H01L21/76828			Delete entire definition
H01L21/76829			Delete entire definition
H01L21/76831			Delete entire definition
H01L21/76832			Delete entire definition
H01L21/76834			Delete entire definition
H01L21/76835			Delete entire definition
H01L21/76837			Delete entire definition
H01L21/76838			Delete entire definition
H01L21/76843			Delete entire definition
H01L21/76844			Delete entire definition
H01L21/76846			Delete entire definition
H01L21/76847			Delete entire definition
H01L21/76849			Delete entire definition
H01L21/7685			Delete entire definition
H01L21/76852			Delete entire definition
H01L21/76853			Delete entire definition
H01L21/76855			Delete entire definition
H01L21/76856			Delete entire definition
H01L21/76858			Delete entire definition
H01L21/76859			Delete entire definition
H01L21/76861			Delete entire definition
H01L21/76862			Delete entire definition
H01L21/76864			Delete entire definition
H01L21/76865			Delete entire definition

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H01L21/76867			Delete entire definition
H01L21/76868			Delete entire definition
H01L21/7687			Delete entire definition
H01L21/76871			Delete entire definition
H01L21/76874			Delete entire definition
H01L21/76879			Delete entire definition
H01L21/7688			Delete entire definition
H01L21/76883			Delete entire definition
H01L21/76885			Delete entire definition
H01L21/76886			Delete entire definition
H01L21/76897			Delete entire definition
H01L21/76898			Delete entire definition
H01L23/00			Delete entire definition
H01L23/02			Delete entire definition
H01L23/055			Delete entire definition
H01L23/12			Delete entire definition
H01L23/147			Delete entire definition
H01L23/16			Delete entire definition
H01L23/20			Delete entire definition
H01L23/22			Delete entire definition
H01L23/24			Delete entire definition
H01L23/28			Delete entire definition
H01L23/295			Delete entire definition
H01L23/3157			Delete entire definition
H01L23/3178			Delete entire definition
H01L23/32			Delete entire definition
H01L23/34			Delete entire definition
H01L23/36			Delete entire definition
H01L23/367			Delete entire definition
H01L23/3672			Delete entire definition
H01L23/3731			Delete entire definition
H01L23/3732			Delete entire definition
H01L23/3733			Delete entire definition
H01L23/3736			Delete entire definition
H01L23/4012			Delete entire definition
H01L23/42			Delete entire definition
H01L23/427			Delete entire definition
H01L23/4334			Delete entire definition
H01L23/44			Delete entire definition
H01L23/46			Delete entire definition
H01L23/467			Delete entire definition
H01L23/473			Delete entire definition
H01L23/4735			Delete entire definition
H01L23/48			Delete entire definition
H01L23/482			Delete entire definition
H01L23/485			Delete entire definition
H01L23/488			Delete entire definition
H01L23/495			Delete entire definition
H01L23/49506			Delete entire definition
H01L23/49544			Delete entire definition
H01L23/49548			Delete entire definition

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H01L23/49572			Delete entire definition
H01L23/498			Delete entire definition
H01L23/49811			Delete entire definition
H01L23/49822			Delete entire definition
H01L23/49827			Delete entire definition
H01L23/4985			Delete entire definition
H01L23/49855			Delete entire definition
H01L23/49861			Delete entire definition
H01L23/49866			Delete entire definition
H01L23/49877			Delete entire definition
H01L23/49883			Delete entire definition
H01L23/50			Delete entire definition
H01L23/5222			Delete entire definition
H01L23/5227			Delete entire definition
H01L23/5228			Delete entire definition
H01L23/528			Delete entire definition
H01L23/53209			Delete entire definition
H01L23/53276			Delete entire definition
H01L23/535			Delete entire definition
H01L23/538			Delete entire definition
H01L23/5383			Delete entire definition
H01L23/5384			Delete entire definition
H01L23/5387			Delete entire definition
H01L23/5388			Delete entire definition
H01L23/544			Delete entire definition
H01L23/552			Delete entire definition
H01L23/58			Delete entire definition
H01L23/585			Delete entire definition
H01L23/60			Delete entire definition
H01L23/642			Delete entire definition
H01L23/645			Delete entire definition
H01L23/647			Delete entire definition
H01L24/00			Delete entire definition
H01L24/02			Delete entire definition
H01L24/06			Delete entire definition
H01L24/10			Delete entire definition
H01L24/11			Delete entire definition
H01L24/12			Delete entire definition
H01L24/14			Delete entire definition
H01L24/18			Delete entire definition
H01L24/26			Delete entire definition
H01L24/27			Delete entire definition
H01L24/34			Delete entire definition
H01L24/50			Delete entire definition
H01L24/71			Delete entire definition
H01L24/80			Delete entire definition
H01L24/82			Delete entire definition
H01L24/85			Delete entire definition
H01L24/93			Delete entire definition
H01L24/96			Delete entire definition
H01L25/00			Delete entire definition

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H01L25/03			Delete entire definition
H01L25/042			Delete entire definition
H01L25/043			Delete entire definition
H01L25/075			Delete entire definition
H01L25/16			Delete entire definition
H01L25/18			Delete entire definition
H01L25/50			Delete entire definition
H01L2223/6644			Delete entire definition
H01L2223/6661			Delete entire definition
H01L2223/6672			Delete entire definition
H01L2223/6677			Delete entire definition
H01L2224/03422			Delete entire definition
H01L2224/03424			Delete entire definition
H01L2224/036			Delete entire definition
H01L2224/0383			Delete entire definition
H01L2224/05187			Delete entire definition
H01L2224/05287			Delete entire definition
H01L2224/05387			Delete entire definition
H01L2224/05487			Delete entire definition
H01L2224/05687			Delete entire definition
H01L2224/05787			Delete entire definition
H01L2224/05887			Delete entire definition
H01L2224/05987			Delete entire definition
H01L2224/0912			Delete entire definition
H01L2224/11422			Delete entire definition
H01L2224/11424			Delete entire definition
H01L2224/116			Delete entire definition
H01L2224/1183			Delete entire definition
H01L2224/13187			Delete entire definition
H01L2224/13287			Delete entire definition
H01L2224/13387			Delete entire definition
H01L2224/13487			Delete entire definition
H01L2224/13687			Delete entire definition
H01L2224/13787			Delete entire definition
H01L2224/13887			Delete entire definition
H01L2224/13987			Delete entire definition
H01L2224/1712			Delete entire definition
H01L2224/27422			Delete entire definition
H01L2224/27424			Delete entire definition
H01L2224/276			Delete entire definition
H01L2224/2783			Delete entire definition
H01L2224/29021			Delete entire definition
H01L2224/29187			Delete entire definition
H01L2224/29287			Delete entire definition
H01L2224/29387			Delete entire definition
H01L2224/29487			Delete entire definition
H01L2224/29687			Delete entire definition
H01L2224/29787			Delete entire definition
H01L2224/29887			Delete entire definition
H01L2224/29987			Delete entire definition
H01L2224/3312			Delete entire definition

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H01L2224/37187			Delete entire definition
H01L2224/37287			Delete entire definition
H01L2224/37387			Delete entire definition
H01L2224/37487			Delete entire definition
H01L2224/37687			Delete entire definition
H01L2224/37787			Delete entire definition
H01L2224/37887			Delete entire definition
H01L2224/37987			Delete entire definition
H01L2224/45187			Delete entire definition
H01L2224/45287			Delete entire definition
H01L2224/45387			Delete entire definition
H01L2224/45487			Delete entire definition
H01L2224/45687			Delete entire definition
H01L2224/45787			Delete entire definition
H01L2224/45887			Delete entire definition
H01L2224/45987			Delete entire definition
H01L2224/48687			Delete entire definition
H01L2224/48787			Delete entire definition
H01L2224/48887			Delete entire definition
H01L2224/80052			Delete entire definition
H01L2224/80237			Delete entire definition
H01L2224/80379			Delete entire definition
H01L2224/80487			Delete entire definition
H01L2224/80587			Delete entire definition
H01L2224/80687			Delete entire definition
H01L2224/80787			Delete entire definition
H01L2224/80901			Delete entire definition
H01L2224/81052			Delete entire definition
H01L2224/81237			Delete entire definition
H01L2224/81379			Delete entire definition
H01L2224/81487			Delete entire definition
H01L2224/81587			Delete entire definition
H01L2224/81687			Delete entire definition
H01L2224/81787			Delete entire definition
H01L2224/81901			Delete entire definition
H01L2224/82237			Delete entire definition
H01L2224/83052			Delete entire definition
H01L2224/83237			Delete entire definition
H01L2224/83379			Delete entire definition
H01L2224/83487			Delete entire definition
H01L2224/83587			Delete entire definition
H01L2224/83687			Delete entire definition
H01L2224/83787			Delete entire definition
H01L2224/84237			Delete entire definition
H01L2224/84487			Delete entire definition
H01L2224/84587			Delete entire definition
H01L2224/84687			Delete entire definition
H01L2224/84787			Delete entire definition
H01L2224/85237			Delete entire definition
H01L2224/85487			Delete entire definition
H01L2224/85587			Delete entire definition

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H01L2224/85687			Delete entire definition
H01L2224/85787			Delete entire definition
H01L2224/86237			Delete entire definition
H01L2225/06541			Delete entire definition
H01L2225/06593			Delete entire definition
H01L2225/06596			Delete entire definition
H01L2225/107			Delete entire definition
H01L2924/06			Delete entire definition
H01L2924/16174			Delete entire definition

Notes:

Use this Definitions Quick Fix (DQF) table to:

- Delete an entire definition
- Delete an entire section
- Change a reference symbol
- Delete a reference symbol
- Delete text in a References section
- Correct one error in spelling, article use, or verb tense

Otherwise, use the standard template.

Reminder: Never delete F symbol definitions.

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3. REVISION CONCORDANCE LIST (RCL)

Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 21/48	<administrative transfer to H10W 99/00>
D	H01L 21/4803	<administrative transfer to H10W 99/00>
D	H01L 21/4807	<administrative transfer to H10W 99/00>
D	H01L 21/481	<administrative transfer to H10W 99/00>
D	H01L 21/4814	<administrative transfer to H10W 99/00>
D	H01L 21/4817	<administrative transfer to H10W 76/01>
D	H01L 21/4821	<administrative transfer to H10W 70/04>
D	H01L 21/4825	<administrative transfer to H10W 70/041>
D	H01L 21/4828	<administrative transfer to H10W 70/042>
D	H01L 21/4832	<administrative transfer to H10W 70/042>
D	H01L 21/4835	<administrative transfer to H10W 70/045>
D	H01L 21/4839	<administrative transfer to H10W 70/047>
D	H01L 21/4842	<administrative transfer to H10W 70/048>
D	H01L 21/4846	<administrative transfer to H10W 70/05>
D	H01L 21/485	<administrative transfer to H10W 70/092>
D	H01L 21/4853	<administrative transfer to H10W 70/093>
D	H01L 21/4857	<administrative transfer to H10W 70/05>
D	H01L 21/486	<administrative transfer to H10W 70/095>
D	H01L 21/4864	<administrative transfer to H10W 70/097>
D	H01L 21/4867	<administrative transfer to H10W 70/098>
D	H01L 21/4871	<administrative transfer to H10W 70/02>
D	H01L 21/4875	<administrative transfer to H10W 70/023>
D	H01L 21/4878	<administrative transfer to H10W 70/027>
D	H01L 21/4882	<administrative transfer to H10W 40/037>
D	H01L 21/4885	<administrative transfer to H10W 72/50>
D	H01L 21/4889	<administrative transfer to H10W 72/075>
D	H01L 21/4892	<administrative transfer to H10W 72/01571>
D	H01L 21/4896	<administrative transfer to H10W 72/015>
D	H01L 21/50	<administrative transfer to H10W 95/00>
D	H01L 21/52	<administrative transfer to H10W 72/071>
D	H01L 21/54	<administrative transfer to H10W 76/05>
D	H01L 21/56	<administrative transfer to H10W 74/01>
D	H01L 21/561	<administrative transfer to H10W 74/014>
D	H01L 21/563	<administrative transfer to H10W 74/012 and H10W 74/15 simultaneously>
D	H01L 21/565	<administrative transfer to H10W 74/016>
D	H01L 21/566	<administrative transfer to H10W 74/017>
D	H01L 21/568	<administrative transfer to H10W 74/019>
D	H01L 21/60	<administrative transfer to H10W 72/071>
D	H01L 2021/60007	<administrative transfer to H10W 72/07236>
D	H01L 2021/60015	<administrative transfer to H10W 72/20>
D	H01L 2021/60022	<administrative transfer to H10W 72/072>
D	H01L 2021/6003	<administrative transfer to H10W 72/0711>
D	H01L 2021/60037	<administrative transfer to H10W 72/07261>
D	H01L 2021/60045	<administrative transfer to H10W 72/07211>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2021/60052	<administrative transfer to H10W 72/07211 and H10W 72/01271 simultaneously>
D	H01L 2021/6006	<administrative transfer to H10W 72/07204>
D	H01L 2021/60067	<administrative transfer to H10W 72/07221>
D	H01L 2021/60075	<administrative transfer to H10W 72/07223>
D	H01L 2021/60082	<administrative transfer to H10W 72/07221>
D	H01L 2021/6009	<administrative transfer to H10W 72/07227>
D	H01L 2021/60097	<administrative transfer to H10W 72/07231>
D	H01L 2021/60105	<administrative transfer to H10W 72/07235>
D	H01L 2021/60112	<administrative transfer to H10W 72/07235>
D	H01L 2021/6012	<administrative transfer to H10W 72/07235>
D	H01L 2021/60127	<administrative transfer to H10W 72/07235>
D	H01L 2021/60135	<administrative transfer to H10W 72/07234>
D	H01L 2021/60142	<administrative transfer to H10W 72/07234>
D	H01L 2021/6015	<administrative transfer to H10W 72/07232>
D	H01L 2021/60157	<administrative transfer to H10W 72/07232>
D	H01L 2021/60165	<administrative transfer to H10W 72/07231>
D	H01L 2021/60172	<administrative transfer to H10W 72/07231>
D	H01L 2021/6018	<administrative transfer to H10W 72/07231>
D	H01L 2021/60187	<administrative transfer to H10W 72/07231>
D	H01L 2021/60195	<administrative transfer to H10W 72/07231>
D	H01L 2021/60202	<administrative transfer to H10W 72/07241>
D	H01L 2021/6021	<administrative transfer to H10W 72/07231>
D	H01L 2021/60217	<administrative transfer to H10W 72/072>
D	H01L 2021/60225	<administrative transfer to H10W 72/072 and H10W 72/247 simultaneously>
D	H01L 2021/60232	<administrative transfer to H10W 72/072 and H10W 72/247 simultaneously>
D	H01L 2021/6024	<administrative transfer to H10W 72/072 and H10W 72/247 simultaneously>
D	H01L 2021/60247	<administrative transfer to H10W 72/072 and H10W 72/247 simultaneously>
D	H01L 2021/60255	<administrative transfer to H10W 72/01212>
D	H01L 2021/60262	<administrative transfer to H10W 72/072 and H10W 72/247 simultaneously>
D	H01L 2021/6027	<administrative transfer to H10W 72/07236>
D	H01L 2021/60277	<administrative transfer to H10W 72/30>
D	H01L 2021/60285	<administrative transfer to H10W 72/071>
D	H01L 2021/60292	<administrative transfer to H10W 72/071>
D	H01L 21/603	<administrative transfer to H10W 72/07232>
D	H01L 21/607	<administrative transfer to H10W 72/07233>
D	H01L 21/71	<administrative transfer to H10W 29/00 and H10W 29/01 simultaneously>
D	H01L 21/74	<administrative transfer to H10W 15/00 and H10W 15/01 simultaneously>
D	H01L 21/743	<administrative transfer to H10W 20/021>
D	H01L 21/746	<administrative transfer to H10W 15/00 and H10W 15/01 simultaneously>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 21/76	<administrative transfer to H10W 10/01 and H10W 10/00 simultaneously>
D	H01L 21/7602	<administrative transfer to H10W 10/01 and H10W 10/00 simultaneously>
D	H01L 21/7605	<administrative transfer to H10W 10/01 and H10W 10/00 simultaneously>
D	H01L 21/7607	<administrative transfer to H10W 10/01 and H10W 10/00 simultaneously>
D	H01L 21/761	<administrative transfer to H10W 10/031 and H10W 10/30 simultaneously>
D	H01L 21/762	<administrative transfer to H10W 10/011 and H10W 10/10 simultaneously>
D	H01L 21/76202	<administrative transfer to H10W 10/012 and H10W 10/13 simultaneously>
D	H01L 21/76205	<administrative transfer to H10W 10/0121 and H10W 10/13 simultaneously>
D	H01L 21/76208	<administrative transfer to H10W 10/0123 and H10W 10/13 simultaneously>
D	H01L 21/7621	<administrative transfer to H10W 10/0124 and H10W 10/13 simultaneously>
D	H01L 21/76213	<administrative transfer to H10W 10/0125 and H10W 10/13 simultaneously>
D	H01L 21/76216	<administrative transfer to H10W 10/0126 and H10W 10/13 simultaneously>
D	H01L 21/76218	<administrative transfer to H10W 10/0127 and H10W 10/13 simultaneously>
D	H01L 21/76221	<administrative transfer to H10W 10/0128 and H10W 10/13 simultaneously>
D	H01L 21/76224	<administrative transfer to H10W 10/014 and H10W 10/17 simultaneously>
D	H01L 21/76227	<administrative transfer to H10W 10/0142 and H10W 10/17 simultaneously>
D	H01L 21/76229	<administrative transfer to H10W 10/0143 and H10W 10/17 simultaneously>
D	H01L 21/76232	<administrative transfer to H10W 10/0145 and H10W 10/17 simultaneously>
D	H01L 21/76235	<administrative transfer to H10W 10/0147 and H10W 10/17 simultaneously>
D	H01L 21/76237	<administrative transfer to H10W 10/0148 and H10W 10/17 simultaneously>
D	H01L 21/76264	<administrative transfer to H10P 90/1906, H10W 10/061 and H10W 10/181 simultaneously>
D	H01L 21/76267	<administrative transfer to H10P 90/1908, H10W 10/061 and H10W 10/181 simultaneously>
D	H01L 21/7627	<administrative transfer to H10P 90/191, H10W 10/061 and H10W 10/181 simultaneously>
D	H01L 21/76272	<administrative transfer to H10P 90/1912, H10W 10/061 and H10W 10/181 simultaneously>
D	H01L 21/76275	<administrative transfer to H10P 90/1914, H10W 10/061 and H10W 10/181 simultaneously>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 21/76278	<administrative transfer to H10P 90/1912, H10W 10/061 and H10W 10/181 simultaneously>
D	H01L 21/76281	<administrative transfer to H10P 90/1906, H10W 10/012, H10W 10/061, H10W 10/13 and H10W 10/181 simultaneously>
D	H01L 21/76283	<administrative transfer to H10P 90/1906, H10W 10/014, H10W 10/061, H10W 10/17 and H10W 10/181 simultaneously>
D	H01L 21/76286	<administrative transfer to H10P 90/1906, H10W 10/061, H10W 10/041, H10W 10/181 and H10W 10/40 simultaneously>
D	H01L 21/76289	<administrative transfer to H10P 90/1906, H10W 10/061, H10W 10/021, H10W 10/181 and H10W 10/20 simultaneously>
D	H01L 21/76291	<administrative transfer to H10P 90/1906, H10W 10/061, H10W 10/051, H10W 10/181 and H10W 10/50 simultaneously>
D	H01L 21/76294	<administrative transfer to H10W 10/018 and H10W 10/10 simultaneously>
D	H01L 21/76297	<administrative transfer to H10W 10/019 and H10W 10/10 simultaneously>
D	H01L 21/763	<administrative transfer to H10W 10/041 and H10W 10/40 simultaneously>
D	H01L 21/764	<administrative transfer to H10W 10/021 and H10W 10/20 simultaneously>
D	H01L 21/765	<administrative transfer to H10W 10/051 and H10W 10/50 simultaneously>
D	H01L 21/768	<administrative transfer to H10W 20/01>
D	H01L 21/76801	<administrative transfer to H10W 20/071>
D	H01L 21/76802	<administrative transfer to H10W 20/081>
D	H01L 21/76804	<administrative transfer to H10W 20/082>
D	H01L 21/76805	<administrative transfer to H10W 20/083>
D	H01L 21/76807	<administrative transfer to H10W 20/084>
D	H01L 21/76808	<administrative transfer to H10W 20/085>
D	H01L 21/7681	<administrative transfer to H10W 20/086>
D	H01L 21/76811	<administrative transfer to H10W 20/087>
D	H01L 21/76813	<administrative transfer to H10W 20/088>
D	H01L 21/76814	<administrative transfer to H10W 20/081>
D	H01L 21/76816	<administrative transfer to H10W 20/089>
D	H01L 21/76817	<administrative transfer to H10W 20/091>
D	H01L 21/76819	<administrative transfer to H10W 20/092>
D	H01L 21/7682	<administrative transfer to H10W 20/072 and H10W 20/46 simultaneously>
D	H01L 21/76822	<administrative transfer to H10W 20/093>
D	H01L 21/76823	<administrative transfer to H10W 20/094>
D	H01L 21/76825	<administrative transfer to H10W 20/095>
D	H01L 21/76826	<administrative transfer to H10W 20/096>
D	H01L 21/76828	<administrative transfer to H10W 20/097>
D	H01L 21/76829	<administrative transfer to H10W 20/074>
D	H01L 21/76831	<administrative transfer to H10W 20/076>
D	H01L 21/76832	<administrative transfer to H10W 20/075>
D	H01L 21/76834	<administrative transfer to H10W 20/077>
D	H01L 21/76835	<administrative transfer to H10W 20/071>
D	H01L 21/76837	<administrative transfer to H10W 20/098>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 21/76838	<administrative transfer to H10W 20/031>
D	H01L 21/7684	<administrative transfer to H10W 20/062>
D	H01L 21/76841	<administrative transfer to H10W 20/032>
D	H01L 21/76843	<administrative transfer to H10W 20/033>
D	H01L 21/76844	<administrative transfer to H10W 20/034>
D	H01L 21/76846	<administrative transfer to H10W 20/035>
D	H01L 21/76847	<administrative transfer to H10W 20/036>
D	H01L 21/76849	<administrative transfer to H10W 20/037>
D	H01L 21/7685	<administrative transfer to H10W 20/038>
D	H01L 21/76852	<administrative transfer to H10W 20/039>
D	H01L 21/76853	<administrative transfer to H10W 20/032>
D	H01L 21/76855	<administrative transfer to H10W 20/047>
D	H01L 21/76856	<administrative transfer to H10W 20/048>
D	H01L 21/76858	<administrative transfer to H10W 20/049>
D	H01L 21/76859	<administrative transfer to H10W 20/051>
D	H01L 21/76861	<administrative transfer to H10W 20/052>
D	H01L 21/76862	<administrative transfer to H10W 20/0523>
D	H01L 21/76864	<administrative transfer to H10W 20/0526>
D	H01L 21/76865	<administrative transfer to H10W 20/054>
D	H01L 21/76867	<administrative transfer to H10W 20/055>
D	H01L 21/76868	<administrative transfer to H10W 20/041>
D	H01L 21/7687	<administrative transfer to H10W 20/046>
D	H01L 21/76871	<administrative transfer to H10W 20/042>
D	H01L 21/76873	<administrative transfer to H10W 20/043>
D	H01L 21/76874	<administrative transfer to H10W 20/044>
D	H01L 21/76876	<administrative transfer to H10W 20/045>
D	H01L 21/76877	<administrative transfer to H10W 20/056>
D	H01L 21/76879	<administrative transfer to H10W 20/057>
D	H01L 21/7688	<administrative transfer to H10W 20/058>
D	H01L 21/76882	<administrative transfer to H10W 20/059>
D	H01L 21/76883	<administrative transfer to H10W 20/056>
D	H01L 21/76885	<administrative transfer to H10W 20/063>
D	H01L 21/76886	<administrative transfer to H10W 20/064>
D	H01L 21/76888	<administrative transfer to H10W 20/065>
D	H01L 21/76889	<administrative transfer to H10W 20/066>
D	H01L 21/76891	<administrative transfer to H10W 20/064>
D	H01L 21/76892	<administrative transfer to H10W 20/067>
D	H01L 21/76894	<administrative transfer to H10W 20/068>
D	H01L 21/76895	<administrative transfer to H10W 20/0698>
D	H01L 21/76897	<administrative transfer to H10W 20/069>
D	H01L 21/76898	<administrative transfer to H10W 20/023>
D	H01L 23/00	<administrative transfer to H10W 99/00>
D	H01L 23/02	<administrative transfer to H10W 76/10>
D	H01L 23/04	<administrative transfer to H10W 76/12>
D	H01L 23/041	<administrative transfer to H10W 76/161>
D	H01L 23/043	<administrative transfer to H10W 76/13>
D	H01L 23/045	<administrative transfer to H10W 76/132>
D	H01L 23/047	<administrative transfer to H10W 76/134>
D	H01L 23/049	<administrative transfer to H10W 76/136>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 23/051	<administrative transfer to H10W 76/138>
D	H01L 23/053	<administrative transfer to H10W 76/15>
D	H01L 23/055	<administrative transfer to H10W 76/153>
D	H01L 23/057	<administrative transfer to H10W 76/157>
D	H01L 23/06	<administrative transfer to H10W 76/17>
D	H01L 23/08	<administrative transfer to H10W 76/18>
D	H01L 23/10	<administrative transfer to H10W 76/60>
D	H01L 23/12	<administrative transfer to H10W 70/60>
D	H01L 23/13	<administrative transfer to H10W 70/68>
D	H01L 23/14	<administrative transfer to H10W 70/69>
D	H01L 23/142	<administrative transfer to H10W 70/6875>
D	H01L 23/145	<administrative transfer to H10W 70/695>
D	H01L 23/147	<administrative transfer to H10W 70/698>
D	H01L 23/15	<administrative transfer to H10W 70/692>
D	H01L 23/16	<administrative transfer to H10W 76/40>
D	H01L 23/18	<administrative transfer to H10W 76/42>
D	H01L 23/20	<administrative transfer to H10W 76/43>
D	H01L 23/22	<administrative transfer to H10W 76/45>
D	H01L 23/24	<administrative transfer to H10W 76/47>
D	H01L 23/26	<administrative transfer to H10W 76/48>
D	H01L 23/28	<administrative transfer to H10W 74/00>
D	H01L 23/29	<administrative transfer to H10W 74/40>
D	H01L 23/291	<administrative transfer to H10W 74/43>
D	H01L 23/293	<administrative transfer to H10W 74/47>
D	H01L 23/295	<administrative transfer to H10W 74/473>
D	H01L 23/296	<administrative transfer to H10W 74/476>
D	H01L 23/298	<administrative transfer to H10W 74/481>
D	H01L 23/31	<administrative transfer to H10W 74/10>
D	H01L 23/3107	<administrative transfer to H10W 74/111>
D	H01L 23/3114	<administrative transfer to H10W 74/129>
D	H01L 23/3121	<administrative transfer to H10W 74/114>
D	H01L 23/3128	<administrative transfer to H10W 74/117>
D	H01L 23/3135	<administrative transfer to H10W 74/121>
D	H01L 23/3142	<administrative transfer to H10W 74/127>
D	H01L 23/315	<administrative transfer to H10W 74/124>
D	H01L 23/3157	<administrative transfer to H10W 74/131>
D	H01L 23/3164	<administrative transfer to H10W 74/144>
D	H01L 23/3171	<administrative transfer to H10W 74/137>
D	H01L 23/3178	<administrative transfer to H10W 74/134>
D	H01L 23/3185	<administrative transfer to H10W 74/141>
D	H01L 23/3192	<administrative transfer to H10W 74/147>
D	H01L 23/32	<administrative transfer to H10W 78/00>
D	H01L 23/34	<administrative transfer to H10W 40/00>
D	H01L 23/345	<administrative transfer to H10W 40/10>
D	H01L 23/36	<administrative transfer to H10W 40/10>
D	H01L 23/367	<administrative transfer to H10W 40/22>
D	H01L 23/3672	<administrative transfer to H10W 40/226>
D	H01L 23/3675	<administrative transfer to H10W 40/22>
D	H01L 23/3677	<administrative transfer to H10W 40/228>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 23/373	<administrative transfer to H10W 40/25>
D	H01L 23/3731	<administrative transfer to H10W 40/259>
D	H01L 23/3732	<administrative transfer to H10W 40/254>
D	H01L 23/3733	<administrative transfer to H10W 40/257>
D	H01L 23/3735	<administrative transfer to H10W 40/255>
D	H01L 23/3736	<administrative transfer to H10W 40/258>
D	H01L 23/3737	<administrative transfer to H10W 40/251>
D	H01L 23/3738	<administrative transfer to H10W 40/253>
D	H01L 23/38	<administrative transfer to H10W 40/28>
D	H01L 23/40	<administrative transfer to H10W 40/60>
D	H01L 23/4006	<administrative transfer to H10W 40/611>
D	H01L 23/4012	<administrative transfer to H10W 40/613>
D	H01L 2023/4018	<administrative transfer to H10W 40/611>
D	H01L 2023/4025	<administrative transfer to H10W 40/611>
D	H01L 2023/4031	<administrative transfer to H10W 40/611>
D	H01L 2023/4037	<administrative transfer to H10W 40/231>
D	H01L 2023/4043	<administrative transfer to H10W 40/233>
D	H01L 2023/405	<administrative transfer to H10W 40/235>
D	H01L 2023/4056	<administrative transfer to H10W 40/237>
D	H01L 2023/4062	<administrative transfer to H10W 40/231>
D	H01L 2023/4068	<administrative transfer to H10W 40/242>
D	H01L 2023/4075	<administrative transfer to H10W 40/60>
D	H01L 2023/4081	<administrative transfer to H10W 40/625>
D	H01L 2023/4087	<administrative transfer to H10W 40/60>
D	H01L 23/4093	<administrative transfer to H10W 40/641>
D	H01L 23/42	<administrative transfer to H10W 40/70>
D	H01L 23/427	<administrative transfer to H10W 40/73>
D	H01L 23/4275	<administrative transfer to H10W 40/735>
D	H01L 23/433	<administrative transfer to H10W 40/77>
D	H01L 23/4332	<administrative transfer to H10W 40/772>
D	H01L 23/4334	<administrative transfer to H10W 40/778>
D	H01L 23/4336	<administrative transfer to H10W 40/776>
D	H01L 23/4338	<administrative transfer to H10W 40/774>
D	H01L 23/44	<administrative transfer to H10W 40/30>
D	H01L 23/445	<administrative transfer to H10W 40/305>
D	H01L 23/46	<administrative transfer to H10W 40/40>
D	H01L 23/467	<administrative transfer to H10W 40/43>
D	H01L 23/473	<administrative transfer to H10W 40/47>
D	H01L 23/4735	<administrative transfer to H10W 40/475>
D	H01L 23/48	<administrative transfer to H10W 72/00>
D	H01L 23/481	<administrative transfer to H10W 20/20>
D	H01L 23/482	<administrative transfer to H10W 20/40>
D	H01L 23/4821	<administrative transfer to H10W 20/483>
D	H01L 23/4822	<administrative transfer to H10W 72/60>
D	H01L 23/4824	<administrative transfer to H10W 20/484>
D	H01L 23/4825	<administrative transfer to H10W 20/40>
D	H01L 23/4827	<administrative transfer to H10W 20/40>
D	H01L 23/4828	<administrative transfer to H10W 20/40>
D	H01L 23/485	<administrative transfer to H10W 20/40>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 23/4855	<administrative transfer to H10W 20/40>
D	H01L 23/488	<administrative transfer to H10W 72/20>
D	H01L 23/49	<administrative transfer to H10W 72/50>
D	H01L 23/492	<administrative transfer to H10W 70/20>
D	H01L 23/4922	<administrative transfer to H10W 70/22>
D	H01L 23/4924	<administrative transfer to H10W 70/24>
D	H01L 23/4926	<administrative transfer to H10W 70/26>
D	H01L 23/4928	<administrative transfer to H10W 70/28>
D	H01L 23/495	<administrative transfer to H10W 70/40>
D	H01L 23/49503	<administrative transfer to H10W 70/411>
D	H01L 23/49506	<administrative transfer to H10W 70/413>
D	H01L 23/4951	<administrative transfer to H10W 70/415>
D	H01L 23/49513	<administrative transfer to H10W 70/417>
D	H01L 23/49517	<administrative transfer to H10W 70/464>
D	H01L 23/4952	<administrative transfer to H10W 70/465>
D	H01L 23/49524	<administrative transfer to H10W 70/466>
D	H01L 23/49527	<administrative transfer to H10W 70/467>
D	H01L 23/49531	<administrative transfer to H10W 70/468>
D	H01L 23/49534	<administrative transfer to H10W 70/451>
D	H01L 23/49537	<administrative transfer to H10W 70/442>
D	H01L 23/49541	<administrative transfer to H10W 70/421>
D	H01L 23/49544	<administrative transfer to H10W 70/433>
D	H01L 23/49548	<administrative transfer to H10W 70/424>
D	H01L 23/49551	<administrative transfer to H10W 70/427>
D	H01L 23/49555	<administrative transfer to H10W 70/429>
D	H01L 23/49558	<administrative transfer to H10W 70/435>
D	H01L 23/49562	<administrative transfer to H10W 70/481>
D	H01L 23/49565	<administrative transfer to H10W 70/438>
D	H01L 23/49568	<administrative transfer to H10W 70/461>
D	H01L 23/49572	<administrative transfer to H10W 70/453>
D	H01L 23/49575	<administrative transfer to H10W 90/811>
D	H01L 23/49579	<administrative transfer to H10W 70/456>
D	H01L 23/49582	<administrative transfer to H10W 70/457>
D	H01L 23/49586	<administrative transfer to H10W 70/458>
D	H01L 23/49589	<administrative transfer to H10W 70/475>
D	H01L 23/49593	<administrative transfer to H10W 70/474>
D	H01L 23/49596	<administrative transfer to H10W 70/476>
D	H01L 23/498	<administrative transfer to H10W 70/60>
D	H01L 23/49805	<administrative transfer to H10W 70/657>
D	H01L 23/49811	<administrative transfer to H10W 90/701>
D	H01L 23/49816	<administrative transfer to H10W 90/701>
D	H01L 23/49822	<administrative transfer to H10W 70/685>
D	H01L 23/49827	<administrative transfer to H10W 70/635>
D	H01L 23/49833	<administrative transfer to H10W 90/401>
D	H01L 23/49838	<administrative transfer to H10W 70/65>
D	H01L 23/49844	<administrative transfer to H10W 70/658>
D	H01L 23/4985	<administrative transfer to H10W 70/688>
D	H01L 23/49855	<administrative transfer to H10W 70/699>
D	H01L 23/49861	<administrative transfer to H10W 70/479>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 23/49866	<administrative transfer to H10W 70/66>
D	H01L 23/49872	<administrative transfer to H10W 70/662>
D	H01L 23/49877	<administrative transfer to H10W 70/664>
D	H01L 23/49883	<administrative transfer to H10W 70/666>
D	H01L 23/49888	<administrative transfer to H10W 70/668>
D	H01L 23/49894	<administrative transfer to H10W 70/69>
D	H01L 23/50	<administrative transfer to H10W 72/00>
D	H01L 23/52	<administrative transfer to H10W 72/00>
D	H01L 23/522	<administrative transfer to H10W 20/40>
D	H01L 23/5221	<administrative transfer to H10W 20/432>
D	H01L 23/5222	<administrative transfer to H10W 20/495>
D	H01L 23/5223	<administrative transfer to H10W 20/496>
D	H01L 23/5225	<administrative transfer to H10W 20/423>
D	H01L 23/5226	<administrative transfer to H10W 20/42>
D	H01L 23/5227	<administrative transfer to H10W 20/497>
D	H01L 23/5228	<administrative transfer to H10W 20/498>
D	H01L 23/525	<administrative transfer to H10W 20/49>
D	H01L 23/5252	<administrative transfer to H10W 20/491>
D	H01L 23/5254	<administrative transfer to H10W 20/492>
D	H01L 23/5256	<administrative transfer to H10W 20/493>
D	H01L 23/5258	<administrative transfer to H10W 20/494>
D	H01L 23/528	<administrative transfer to H10W 20/43>
D	H01L 23/5283	<administrative transfer to H10W 20/435>
D	H01L 23/5286	<administrative transfer to H10W 20/427>
D	H01L 23/532	<administrative transfer to H10W 20/48>
D	H01L 23/53204	<administrative transfer to H10W 20/44>
D	H01L 23/53209	<administrative transfer to H10W 20/4403>
D	H01L 23/53214	<administrative transfer to H10W 20/4405>
D	H01L 23/53219	<administrative transfer to H10W 20/4407>
D	H01L 23/53223	<administrative transfer to H10W 20/425>
D	H01L 23/53228	<administrative transfer to H10W 20/4421>
D	H01L 23/53233	<administrative transfer to H10W 20/4424>
D	H01L 23/53238	<administrative transfer to H10W 20/425>
D	H01L 23/53242	<administrative transfer to H10W 20/4432>
D	H01L 23/53247	<administrative transfer to H10W 20/4435>
D	H01L 23/53252	<administrative transfer to H10W 20/425>
D	H01L 23/53257	<administrative transfer to H10W 20/4441>
D	H01L 23/53261	<administrative transfer to H10W 20/4446>
D	H01L 23/53266	<administrative transfer to H10W 20/425>
D	H01L 23/53271	<administrative transfer to H10W 20/4451>
D	H01L 23/53276	<administrative transfer to H10W 20/4462>
D	H01L 23/5328	<administrative transfer to H10W 20/4473>
D	H01L 23/53285	<administrative transfer to H10W 20/4484>
D	H01L 23/5329	<administrative transfer to H10W 20/48>
D	H01L 23/53295	<administrative transfer to H10W 20/47>
D	H01L 23/535	<administrative transfer to H10W 20/20>
D	H01L 23/538	<administrative transfer to H10W 70/60 and H10W 70/611 simultaneously>
D	H01L 23/5381	<administrative transfer to H10W 70/65>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 23/5382	<administrative transfer to H10W 70/641 and H10W 70/611 simultaneously>
D	H01L 23/5383	<administrative transfer to H10W 70/685 and H10W 70/611 simultaneously>
D	H01L 23/5384	<administrative transfer to H10W 70/635 and H10W 70/611 simultaneously>
D	H01L 23/5385	<administrative transfer to H10W 70/611 and H10W 90/401 simultaneously>
D	H01L 23/5386	<administrative transfer to H10W 70/65 and H10W 70/611 simultaneously>
D	H01L 23/5387	<administrative transfer to H10W 70/688 and H10W 70/611 simultaneously>
D	H01L 23/5388	<administrative transfer to H10W 70/699 and H10W 70/611 simultaneously>
D	H01L 23/5389	<administrative transfer to H10W 70/614>
D	H01L 23/544	<administrative transfer to H10W 46/00>
D	H01L 23/552	<administrative transfer to H10W 42/20>
D	H01L 23/556	<administrative transfer to H10W 42/25>
D	H01L 23/562	<administrative transfer to H10W 42/121>
D	H01L 23/564	<administrative transfer to H10W 42/00>
D	H01L 23/57	<administrative transfer to H10W 42/40>
D	H01L 23/573	<administrative transfer to H10W 42/40>
D	H01L 23/576	<administrative transfer to H10W 42/405>
D	H01L 23/58	<administrative transfer to H10W 42/00>
D	H01L 23/585	<administrative transfer to H10W 42/00>
D	H01L 23/60	<administrative transfer to H10W 42/60>
D	H01L 23/62	<administrative transfer to H10W 42/80>
D	H01L 23/64	<administrative transfer to H10W 44/00>
D	H01L 23/642	<administrative transfer to H10W 44/601>
D	H01L 23/645	<administrative transfer to H10W 44/501>
D	H01L 23/647	<administrative transfer to H10W 44/401>
D	H01L 23/66	<administrative transfer to H10W 44/20>
D	H01L 24/00	<administrative transfer to H10W 72/00>
D	H01L 24/01	<administrative transfer to H10W 72/00>
D	H01L 24/02	<administrative transfer to H10W 72/90>
D	H01L 24/03	<administrative transfer to H10W 72/019>
D	H01L 24/04	<administrative transfer to H10W 72/90>
D	H01L 24/05	<administrative transfer to H10W 72/90>
D	H01L 24/06	<administrative transfer to H10W 72/90>
D	H01L 24/07	<administrative transfer to H10W 72/90>
D	H01L 24/08	<administrative transfer to H10W 72/90>
D	H01L 24/09	<administrative transfer to H10W 72/90>
D	H01L 24/10	<administrative transfer to H10W 72/20>
D	H01L 24/11	<administrative transfer to H10W 72/012>
D	H01L 24/12	<administrative transfer to H10W 72/20>
D	H01L 24/13	<administrative transfer to H10W 72/20>
D	H01L 24/14	<administrative transfer to H10W 72/20>
D	H01L 24/15	<administrative transfer to H10W 72/20>
D	H01L 24/16	<administrative transfer to H10W 72/20>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 24/17	<administrative transfer to H10W 72/20>
D	H01L 24/18	<administrative transfer to H10W 70/60>
D	H01L 24/19	<administrative transfer to H10W 70/09>
D	H01L 24/20	<administrative transfer to H10W 70/60>
D	H01L 24/23	<administrative transfer to H10W 70/60>
D	H01L 24/24	<administrative transfer to H10W 70/60>
D	H01L 24/25	<administrative transfer to H10W 70/60>
D	H01L 24/26	<administrative transfer to H10W 72/30>
D	H01L 24/27	<administrative transfer to H10W 72/013>
D	H01L 24/28	<administrative transfer to H10W 72/30>
D	H01L 24/29	<administrative transfer to H10W 72/30>
D	H01L 24/30	<administrative transfer to H10W 72/30>
D	H01L 24/31	<administrative transfer to H10W 72/30>
D	H01L 24/32	<administrative transfer to H10W 72/30>
D	H01L 24/33	<administrative transfer to H10W 72/30>
D	H01L 24/34	<administrative transfer to H10W 72/60>
D	H01L 24/35	<administrative transfer to H10W 72/016>
D	H01L 24/36	<administrative transfer to H10W 72/60>
D	H01L 24/37	<administrative transfer to H10W 72/60>
D	H01L 24/38	<administrative transfer to H10W 72/60>
D	H01L 24/39	<administrative transfer to H10W 72/60>
D	H01L 24/40	<administrative transfer to H10W 72/60>
D	H01L 24/41	<administrative transfer to H10W 72/60>
D	H01L 24/42	<administrative transfer to H10W 72/50>
D	H01L 24/43	<administrative transfer to H10W 72/015>
D	H01L 24/44	<administrative transfer to H10W 72/50>
D	H01L 24/45	<administrative transfer to H10W 72/50>
D	H01L 24/46	<administrative transfer to H10W 72/50>
D	H01L 24/47	<administrative transfer to H10W 72/50>
D	H01L 24/48	<administrative transfer to H10W 72/50>
D	H01L 24/49	<administrative transfer to H10W 72/50>
D	H01L 24/50	<administrative transfer to H10W 72/701>
D	H01L 24/63	<administrative transfer to H10W 72/00>
D	H01L 24/64	<administrative transfer to H10W 72/01>
D	H01L 24/65	<administrative transfer to H10W 72/00>
D	H01L 24/66	<administrative transfer to H10W 72/00>
D	H01L 24/67	<administrative transfer to H10W 72/00>
D	H01L 24/68	<administrative transfer to H10W 72/00>
D	H01L 24/69	<administrative transfer to H10W 72/00>
D	H01L 24/70	<administrative transfer to H10W 72/00>
D	H01L 24/71	<administrative transfer to H10W 72/00>
D	H01L 24/72	<administrative transfer to H10W 72/00>
D	H01L 24/73	<administrative transfer to H10W 72/851>
D	H01L 24/74	<administrative transfer to H10W 72/011>
D	H01L 24/741	<administrative transfer to H10W 72/011>
D	H01L 24/742	<administrative transfer to H10W 72/0112>
D	H01L 24/743	<administrative transfer to H10W 72/0113>
D	H01L 24/744	<administrative transfer to H10W 72/0116>
D	H01L 24/745	<administrative transfer to H10W 72/0115>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 24/75	<administrative transfer to H10W 72/0711>
D	H01L 24/76	<administrative transfer to H10W 72/0711>
D	H01L 24/77	<administrative transfer to H10W 72/0711>
D	H01L 24/78	<administrative transfer to H10W 72/0711>
D	H01L 24/79	<administrative transfer to H10W 72/0711>
D	H01L 24/799	<administrative transfer to H10W 72/0711>
D	H01L 24/80	<administrative transfer to H10W 99/00>
D	H01L 24/81	<administrative transfer to H10W 72/072>
D	H01L 24/82	<administrative transfer to H10W 70/093>
D	H01L 24/83	<administrative transfer to H10W 72/073>
D	H01L 24/84	<administrative transfer to H10W 72/076>
D	H01L 24/85	<administrative transfer to H10W 72/075>
D	H01L 24/86	<administrative transfer to H10W 72/077>
D	H01L 24/89	<administrative transfer to H10W 72/00>
D	H01L 24/90	<administrative transfer to H10W 72/00>
D	H01L 24/91	<administrative transfer to H10W 99/00>
D	H01L 24/92	<administrative transfer to H10W 99/00>
D	H01L 24/93	<administrative transfer to H10W 72/0198>
D	H01L 24/94	<administrative transfer to H10W 72/0198>
D	H01L 24/95	<administrative transfer to H10W 72/0198>
D	H01L 24/96	<administrative transfer to H10W 72/0198>
D	H01L 24/97	<administrative transfer to H10W 72/0198>
D	H01L 24/98	<administrative transfer to H10W 72/071>
D	H01L 25/00	<administrative transfer to H10W 90/00>
D	H01L 25/03	<administrative transfer to H10W 90/00>
D	H01L 25/04	<administrative transfer to H10W 90/00>
D	H01L 25/041	<administrative transfer to H10W 90/00>
D	H01L 25/042	<administrative transfer to H10W 90/00>
D	H01L 25/043	<administrative transfer to H10W 90/00>
D	H01L 25/065	<administrative transfer to H10W 90/00>
D	H01L 25/0652	<administrative transfer to H10W 90/00>
D	H01L 25/0655	<administrative transfer to H10W 90/00>
D	H01L 25/0657	<administrative transfer to H10W 90/00>
D	H01L 25/07	<administrative transfer to H10W 90/00>
D	H01L 25/071	<administrative transfer to H10W 90/00>
D	H01L 25/072	<administrative transfer to H10W 90/00>
D	H01L 25/073	<administrative transfer to H10W 90/00>
D	H01L 25/074	<administrative transfer to H10W 90/00>
D	H01L 25/075	<administrative transfer to H10W 90/00>
D	H01L 25/0753	<administrative transfer to H10W 90/00>
D	H01L 25/0756	<administrative transfer to H10W 90/00>
D	H01L 25/10	<administrative transfer to H10W 90/00>
D	H01L 25/105	<administrative transfer to H10W 90/00>
D	H01L 25/11	<administrative transfer to H10W 90/00>
D	H01L 25/112	<administrative transfer to H10W 90/00>
D	H01L 25/115	<administrative transfer to H10W 90/00>
D	H01L 25/117	<administrative transfer to H10W 90/00>
D	H01L 25/13	<administrative transfer to H10W 90/00>
D	H01L 25/16	<administrative transfer to H10W 90/00>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 25/162	<administrative transfer to H10W 90/00>
D	H01L 25/165	<administrative transfer to H10W 90/00>
D	H01L 25/167	<administrative transfer to H10W 90/00>
D	H01L 25/18	<administrative transfer to H10W 90/00>
D	H01L 25/50	<administrative transfer to H10W 90/00>
D	H01L 2221/10	<administrative transfer to H10W 20/01>
D	H01L 2221/1005	<administrative transfer to H10W 20/071>
D	H01L 2221/101	<administrative transfer to H10W 20/081>
D	H01L 2221/1015	<administrative transfer to H10W 20/084>
D	H01L 2221/1021	<administrative transfer to H10W 20/0882>
D	H01L 2221/1026	<administrative transfer to H10W 20/0884>
D	H01L 2221/1031	<administrative transfer to H10W 20/0886>
D	H01L 2221/1036	<administrative transfer to H10W 20/0888>
D	H01L 2221/1042	<administrative transfer to H10W 20/072>
D	H01L 2221/1047	<administrative transfer to H10W 20/072>
D	H01L 2221/1052	<administrative transfer to H10W 20/074>
D	H01L 2221/1057	<administrative transfer to H10W 20/076>
D	H01L 2221/1063	<administrative transfer to H10W 20/0765>
D	H01L 2221/1068	<administrative transfer to H10W 20/031>
D	H01L 2221/1073	<administrative transfer to H10W 20/032>
D	H01L 2221/1078	<administrative transfer to H10W 20/0375>
D	H01L 2221/1084	<administrative transfer to H10W 20/042>
D	H01L 2221/1089	<administrative transfer to H10W 20/0425>
D	H01L 2221/1094	<administrative transfer to H10W 20/0554>
D	H01L 2223/00	<administrative transfer to H10W 99/00>
D	H01L 2223/544	<administrative transfer to H10W 46/00>
D	H01L 2223/54406	<administrative transfer to H10W 46/103>
D	H01L 2223/54413	<administrative transfer to H10W 46/106>
D	H01L 2223/5442	<administrative transfer to H10W 46/101>
D	H01L 2223/54426	<administrative transfer to H10W 46/301>
D	H01L 2223/54433	<administrative transfer to H10W 46/401>
D	H01L 2223/5444	<administrative transfer to H10W 46/403>
D	H01L 2223/54446	<administrative transfer to H10W 46/407>
D	H01L 2223/54453	<administrative transfer to H10W 46/501>
D	H01L 2223/5446	<administrative transfer to H10W 46/503>
D	H01L 2223/54466	<administrative transfer to H10W 46/507>
D	H01L 2223/54473	<administrative transfer to H10W 46/601>
D	H01L 2223/5448	<administrative transfer to H10W 46/603>
D	H01L 2223/54486	<administrative transfer to H10W 46/607>
D	H01L 2223/54493	<administrative transfer to H10W 46/201>
D	H01L 2223/58	<administrative transfer to H10W 42/00>
D	H01L 2223/64	<administrative transfer to H10W 44/00>
D	H01L 2223/66	<administrative transfer to H10W 44/20>
D	H01L 2223/6605	<administrative transfer to H10W 44/203>
D	H01L 2223/6611	<administrative transfer to H10W 44/206>
D	H01L 2223/6616	<administrative transfer to H10W 44/209>
D	H01L 2223/6622	<administrative transfer to H10W 44/212>
D	H01L 2223/6627	<administrative transfer to H10W 44/216>
D	H01L 2223/6633	<administrative transfer to H10W 44/219>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2223/6638	<administrative transfer to H10W 44/223>
D	H01L 2223/6644	<administrative transfer to H10W 44/226>
D	H01L 2223/665	<administrative transfer to H10W 44/231>
D	H01L 2223/6655	<administrative transfer to H10W 44/234>
D	H01L 2223/6661	<administrative transfer to H10W 44/241>
D	H01L 2223/6666	<administrative transfer to H10W 44/243>
D	H01L 2223/6672	<administrative transfer to H10W 44/241>
D	H01L 2223/6677	<administrative transfer to H10W 44/248>
D	H01L 2223/6683	<administrative transfer to H10W 44/251>
D	H01L 2223/6688	<administrative transfer to H10W 44/255>
D	H01L 2223/6694	<administrative transfer to H10W 44/259>
D	H01L 2224/00	<administrative transfer to H10W 72/00>
D	H01L 2224/01	<administrative transfer to H10W 72/00>
D	H01L 2224/02	<administrative transfer to H10W 72/90>
D	H01L 2224/0212	<administrative transfer to H10W 72/981>
D	H01L 2224/02122	<administrative transfer to H10W 72/981>
D	H01L 2224/02123	<administrative transfer to H10W 72/981>
D	H01L 2224/02125	<administrative transfer to H10W 72/983>
D	H01L 2224/02126	<administrative transfer to H10W 72/983>
D	H01L 2224/0213	<administrative transfer to H10W 72/985>
D	H01L 2224/02135	<administrative transfer to H10W 72/987>
D	H01L 2224/0214	<administrative transfer to H10W 72/981>
D	H01L 2224/02141	<administrative transfer to H10W 72/981>
D	H01L 2224/02145	<administrative transfer to H10W 72/981>
D	H01L 2224/0215	<administrative transfer to H10W 72/981>
D	H01L 2224/02163	<administrative transfer to H10W 72/981>
D	H01L 2224/02165	<administrative transfer to H10W 72/983>
D	H01L 2224/02166	<administrative transfer to H10W 72/983>
D	H01L 2224/0217	<administrative transfer to H10W 72/985>
D	H01L 2224/02175	<administrative transfer to H10W 72/987>
D	H01L 2224/0218	<administrative transfer to H10W 72/981>
D	H01L 2224/02181	<administrative transfer to H10W 72/981>
D	H01L 2224/02185	<administrative transfer to H10W 72/981>
D	H01L 2224/0219	<administrative transfer to H10W 72/981>
D	H01L 2224/022	<administrative transfer to H10W 72/981>
D	H01L 2224/02205	<administrative transfer to H10W 72/981>
D	H01L 2224/02206	<administrative transfer to H10W 72/981>
D	H01L 2224/0221	<administrative transfer to H10W 72/981>
D	H01L 2224/02215	<administrative transfer to H10W 72/981>
D	H01L 2224/02233	<administrative transfer to H10W 72/981>
D	H01L 2224/02235	<administrative transfer to H10W 72/983>
D	H01L 2224/0224	<administrative transfer to H10W 72/985>
D	H01L 2224/02245	<administrative transfer to H10W 72/987>
D	H01L 2224/0225	<administrative transfer to H10W 72/981>
D	H01L 2224/02251	<administrative transfer to H10W 72/981>
D	H01L 2224/02255	<administrative transfer to H10W 72/981>
D	H01L 2224/0226	<administrative transfer to H10W 72/981>
D	H01L 2224/023	<administrative transfer to H10W 70/60>
D	H01L 2224/0231	<administrative transfer to H10W 70/05>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/02311	<administrative transfer to H10W 70/05>
D	H01L 2224/02313	<administrative transfer to H10W 70/05>
D	H01L 2224/02315	<administrative transfer to H10W 70/05>
D	H01L 2224/02317	<administrative transfer to H10W 70/05>
D	H01L 2224/02319	<administrative transfer to H10W 70/05>
D	H01L 2224/02321	<administrative transfer to H10W 70/05>
D	H01L 2224/0233	<administrative transfer to H10W 70/60>
D	H01L 2224/02331	<administrative transfer to H10W 70/60>
D	H01L 2224/02333	<administrative transfer to H10W 70/60>
D	H01L 2224/02335	<administrative transfer to H10W 70/60>
D	H01L 2224/0235	<administrative transfer to H10W 70/65>
D	H01L 2224/02351	<administrative transfer to H10W 70/65>
D	H01L 2224/0236	<administrative transfer to H10W 70/68>
D	H01L 2224/0237	<administrative transfer to H10W 70/65>
D	H01L 2224/02371	<administrative transfer to H10W 70/65>
D	H01L 2224/02372	<administrative transfer to H10W 70/65>
D	H01L 2224/02373	<administrative transfer to H10W 70/65>
D	H01L 2224/02375	<administrative transfer to H10W 70/654>
D	H01L 2224/02377	<administrative transfer to H10W 70/656>
D	H01L 2224/02379	<administrative transfer to H10W 70/655>
D	H01L 2224/02381	<administrative transfer to H10W 70/652>
D	H01L 2224/0239	<administrative transfer to H10W 70/66>
D	H01L 2224/024	<administrative transfer to H10W 70/69>
D	H01L 2224/03	<administrative transfer to H10W 72/019>
D	H01L 2224/03001	<administrative transfer to H10W 72/01904>
D	H01L 2224/03002	<administrative transfer to H10W 72/01904>
D	H01L 2224/03003	<administrative transfer to H10W 72/01904>
D	H01L 2224/03005	<administrative transfer to H10W 72/01904>
D	H01L 2224/03009	<administrative transfer to H10W 72/01904>
D	H01L 2224/03011	<administrative transfer to H10W 72/01908>
D	H01L 2224/03013	<administrative transfer to H10W 72/01908>
D	H01L 2224/03015	<administrative transfer to H10W 72/01908>
D	H01L 2224/03019	<administrative transfer to H10W 72/01908>
D	H01L 2224/031	<administrative transfer to H10W 72/019>
D	H01L 2224/0311	<administrative transfer to H10W 72/019>
D	H01L 2224/0312	<administrative transfer to H10W 72/019 and H10W 72/923 simultaneously>
D	H01L 2224/033	<administrative transfer to H10W 72/01921>
D	H01L 2224/0331	<administrative transfer to H10W 72/01923>
D	H01L 2224/03312	<administrative transfer to H10W 72/01923>
D	H01L 2224/03318	<administrative transfer to H10W 72/01923>
D	H01L 2224/0332	<administrative transfer to H10W 72/01923>
D	H01L 2224/0333	<administrative transfer to H10W 72/01925>
D	H01L 2224/03332	<administrative transfer to H10W 72/01925>
D	H01L 2224/03334	<administrative transfer to H10W 72/01925>
D	H01L 2224/034	<administrative transfer to H10W 72/01931>
D	H01L 2224/0341	<administrative transfer to H10W 72/01933>
D	H01L 2224/03416	<administrative transfer to H10W 72/01933>
D	H01L 2224/03418	<administrative transfer to H10W 72/01933>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/0342	<administrative transfer to H10W 72/01933>
D	H01L 2224/03422	<administrative transfer to H10W 72/01933>
D	H01L 2224/03424	<administrative transfer to H10W 72/01933>
D	H01L 2224/03426	<administrative transfer to H10W 72/01933>
D	H01L 2224/03428	<administrative transfer to H10W 72/01933>
D	H01L 2224/0343	<administrative transfer to H10W 72/01936>
D	H01L 2224/03436	<administrative transfer to H10W 72/01936>
D	H01L 2224/03438	<administrative transfer to H10W 72/01936>
D	H01L 2224/0344	<administrative transfer to H10W 72/01936>
D	H01L 2224/03442	<administrative transfer to H10W 72/01936>
D	H01L 2224/03444	<administrative transfer to H10W 72/01938>
D	H01L 2224/0345	<administrative transfer to H10W 72/01938>
D	H01L 2224/03452	<administrative transfer to H10W 72/01938>
D	H01L 2224/0346	<administrative transfer to H10W 72/01935>
D	H01L 2224/03462	<administrative transfer to H10W 72/01935>
D	H01L 2224/03464	<administrative transfer to H10W 72/01935>
D	H01L 2224/03466	<administrative transfer to H10W 72/01931>
D	H01L 2224/0347	<administrative transfer to H10W 72/01955>
D	H01L 2224/03472	<administrative transfer to H10W 72/01955>
D	H01L 2224/03474	<administrative transfer to H10W 72/01955>
D	H01L 2224/0348	<administrative transfer to H10W 72/01955>
D	H01L 2224/035	<administrative transfer to H10W 72/01961>
D	H01L 2224/03502	<administrative transfer to H10W 72/01961>
D	H01L 2224/03505	<administrative transfer to H10W 72/01961>
D	H01L 2224/0351	<administrative transfer to H10W 72/01961>
D	H01L 2224/03515	<administrative transfer to H10W 72/01961>
D	H01L 2224/0352	<administrative transfer to H10W 72/01961>
D	H01L 2224/03522	<administrative transfer to H10W 72/01961>
D	H01L 2224/03524	<administrative transfer to H10W 72/01961>
D	H01L 2224/0355	<administrative transfer to H10W 72/01961>
D	H01L 2224/03552	<administrative transfer to H10W 72/01961>
D	H01L 2224/03554	<administrative transfer to H10W 72/01961>
D	H01L 2224/036	<administrative transfer to H10W 72/01951>
D	H01L 2224/03602	<administrative transfer to H10W 72/01951>
D	H01L 2224/0361	<administrative transfer to H10W 72/01953>
D	H01L 2224/03612	<administrative transfer to H10W 72/01953>
D	H01L 2224/03614	<administrative transfer to H10W 72/01953>
D	H01L 2224/03616	<administrative transfer to H10W 72/01953>
D	H01L 2224/03618	<administrative transfer to H10W 72/01951>
D	H01L 2224/0362	<administrative transfer to H10W 72/01951>
D	H01L 2224/03622	<administrative transfer to H10W 72/01951>
D	H01L 2224/0363	<administrative transfer to H10W 72/01951>
D	H01L 2224/03632	<administrative transfer to H10W 72/01951>
D	H01L 2224/037	<administrative transfer to H10W 72/019>
D	H01L 2224/038	<administrative transfer to H10W 72/019>
D	H01L 2224/0381	<administrative transfer to H10W 72/01971>
D	H01L 2224/0382	<administrative transfer to H10W 72/019 and H10W 72/923 simultaneously>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/03821	<administrative transfer to H10W 72/019 and H10W 72/923 simultaneously>
D	H01L 2224/03822	<administrative transfer to H10W 72/019 and H10W 72/923 simultaneously>
D	H01L 2224/03823	<administrative transfer to H10W 72/019 and H10W 72/923 simultaneously>
D	H01L 2224/03824	<administrative transfer to H10W 72/019 and H10W 72/923 simultaneously>
D	H01L 2224/03825	<administrative transfer to H10W 72/019 and H10W 72/923 simultaneously>
D	H01L 2224/03826	<administrative transfer to H10W 72/019 and H10W 72/923 simultaneously>
D	H01L 2224/03827	<administrative transfer to H10W 72/019 and H10W 72/923 simultaneously>
D	H01L 2224/03828	<administrative transfer to H10W 72/019>
D	H01L 2224/03829	<administrative transfer to H10W 72/019>
D	H01L 2224/0383	<administrative transfer to H10W 72/01951>
D	H01L 2224/03831	<administrative transfer to H10W 72/01953>
D	H01L 2224/0384	<administrative transfer to H10W 72/01951>
D	H01L 2224/03845	<administrative transfer to H10W 72/01951>
D	H01L 2224/03848	<administrative transfer to H10W 72/019>
D	H01L 2224/03849	<administrative transfer to H10W 72/01951>
D	H01L 2224/039	<administrative transfer to H10W 72/019>
D	H01L 2224/03901	<administrative transfer to H10W 72/019>
D	H01L 2224/03902	<administrative transfer to H10W 72/019>
D	H01L 2224/03903	<administrative transfer to H10W 72/019>
D	H01L 2224/03906	<administrative transfer to H10W 72/019>
D	H01L 2224/0391	<administrative transfer to H10W 72/019>
D	H01L 2224/03912	<administrative transfer to H10W 72/019>
D	H01L 2224/03914	<administrative transfer to H10W 72/019>
D	H01L 2224/03916	<administrative transfer to H10W 72/019>
D	H01L 2224/0392	<administrative transfer to H10W 72/019>
D	H01L 2224/03921	<administrative transfer to H10W 72/019>
D	H01L 2224/04	<administrative transfer to H10W 72/90>
D	H01L 2224/0401	<administrative transfer to H10W 72/29>
D	H01L 2224/04026	<administrative transfer to H10W 72/59>
D	H01L 2224/04034	<administrative transfer to H10W 72/691>
D	H01L 2224/04042	<administrative transfer to H10W 72/59>
D	H01L 2224/0405	<administrative transfer to H10W 72/709>
D	H01L 2224/04073	<administrative transfer to H10W 72/90>
D	H01L 2224/04105	<administrative transfer to H10W 72/9413>
D	H01L 2224/05	<administrative transfer to H10W 72/90>
D	H01L 2224/05001	<administrative transfer to H10W 72/923>
D	H01L 2224/05005	<administrative transfer to H10W 72/923 and H10W 72/921 simultaneously>
D	H01L 2224/05006	<administrative transfer to H10W 72/923 and H10W 72/921 simultaneously>
D	H01L 2224/05007	<administrative transfer to H10W 72/923>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/05008	<administrative transfer to H10W 72/923 and H10W 72/9223 simultaneously>
D	H01L 2224/05009	<administrative transfer to H10W 72/923 and H10W 72/9226 simultaneously>
D	H01L 2224/0501	<administrative transfer to H10W 72/923 and H10W 72/931 simultaneously>
D	H01L 2224/05011	<administrative transfer to H10W 72/923>
D	H01L 2224/05012	<administrative transfer to H10W 72/923 and H10W 72/932 simultaneously>
D	H01L 2224/05013	<administrative transfer to H10W 72/923 and H10W 72/932 simultaneously>
D	H01L 2224/05014	<administrative transfer to H10W 72/923 and H10W 72/932 simultaneously>
D	H01L 2224/05015	<administrative transfer to H10W 72/923 and H10W 72/932 simultaneously>
D	H01L 2224/05016	<administrative transfer to H10W 72/923 and H10W 72/934 simultaneously>
D	H01L 2224/05017	<administrative transfer to H10W 72/923 and H10W 72/934 simultaneously>
D	H01L 2224/05018	<administrative transfer to H10W 72/923 and H10W 72/934 simultaneously>
D	H01L 2224/05019	<administrative transfer to H10W 72/923 and H10W 72/934 simultaneously>
D	H01L 2224/0502	<administrative transfer to H10W 72/923 and H10W 72/941 simultaneously>
D	H01L 2224/05022	<administrative transfer to H10W 72/923 and H10W 72/9415 simultaneously>
D	H01L 2224/05023	<administrative transfer to H10W 72/923 and H10W 72/9415 simultaneously>
D	H01L 2224/05024	<administrative transfer to H10W 72/923 and H10W 72/942 simultaneously>
D	H01L 2224/05025	<administrative transfer to H10W 72/923 and H10W 72/942 simultaneously>
D	H01L 2224/05026	<administrative transfer to H10W 72/923 and H10W 72/9415 simultaneously>
D	H01L 2224/05027	<administrative transfer to H10W 72/923 and H10W 72/9415 simultaneously>
D	H01L 2224/05073	<administrative transfer to H10W 72/923>
D	H01L 2224/05075	<administrative transfer to H10W 72/923>
D	H01L 2224/05076	<administrative transfer to H10W 72/923 and H10W 72/921 simultaneously>
D	H01L 2224/05078	<administrative transfer to H10W 72/923 and H10W 72/924 simultaneously>
D	H01L 2224/0508	<administrative transfer to H10W 72/923>
D	H01L 2224/05082	<administrative transfer to H10W 72/923>
D	H01L 2224/05083	<administrative transfer to H10W 72/923>
D	H01L 2224/05084	<administrative transfer to H10W 72/923>
D	H01L 2224/05085	<administrative transfer to H10W 72/923 and H10W 72/9232 simultaneously>
D	H01L 2224/05086	<administrative transfer to H10W 72/9232>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/05087	<administrative transfer to H10W 72/9232>
D	H01L 2224/05088	<administrative transfer to H10W 72/9232>
D	H01L 2224/05089	<administrative transfer to H10W 72/9232>
D	H01L 2224/0509	<administrative transfer to H10W 72/9232>
D	H01L 2224/05091	<administrative transfer to H10W 72/9232>
D	H01L 2224/05092	<administrative transfer to H10W 72/9232>
D	H01L 2224/05093	<administrative transfer to H10W 72/9232>
D	H01L 2224/05094	<administrative transfer to H10W 72/9232>
D	H01L 2224/05095	<administrative transfer to H10W 72/9232>
D	H01L 2224/05096	<administrative transfer to H10W 72/9232>
D	H01L 2224/05097	<administrative transfer to H10W 72/9232>
D	H01L 2224/05098	<administrative transfer to H10W 72/923 and H10W 72/9232 simultaneously>
D	H01L 2224/05099	<administrative transfer to H10W 72/923 and H10W 72/951 simultaneously>
D	H01L 2224/051	<administrative transfer to H10W 72/923 and H10W 72/952 simultaneously>
D	H01L 2224/05101	<administrative transfer to H10W 72/923 and H10W 72/952 simultaneously>
D	H01L 2224/05105	<administrative transfer to H10W 72/923 and H10W 72/952 simultaneously>
D	H01L 2224/05109	<administrative transfer to H10W 72/923 and H10W 72/952 simultaneously>
D	H01L 2224/05111	<administrative transfer to H10W 72/923 and H10W 72/952 simultaneously>
D	H01L 2224/05113	<administrative transfer to H10W 72/923 and H10W 72/952 simultaneously>
D	H01L 2224/05114	<administrative transfer to H10W 72/923 and H10W 72/952 simultaneously>
D	H01L 2224/05116	<administrative transfer to H10W 72/923 and H10W 72/952 simultaneously>
D	H01L 2224/05117	<administrative transfer to H10W 72/923 and H10W 72/952 simultaneously>
D	H01L 2224/05118	<administrative transfer to H10W 72/923 and H10W 72/952 simultaneously>
D	H01L 2224/0512	<administrative transfer to H10W 72/923 and H10W 72/952 simultaneously>
D	H01L 2224/05123	<administrative transfer to H10W 72/923 and H10W 72/952 simultaneously>
D	H01L 2224/05124	<administrative transfer to H10W 72/923 and H10W 72/952 simultaneously>
D	H01L 2224/05138	<administrative transfer to H10W 72/923 and H10W 72/952 simultaneously>
D	H01L 2224/05139	<administrative transfer to H10W 72/923 and H10W 72/952 simultaneously>
D	H01L 2224/05144	<administrative transfer to H10W 72/923 and H10W 72/952 simultaneously>
D	H01L 2224/05147	<administrative transfer to H10W 72/923 and H10W 72/952 simultaneously>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/05149	<administrative transfer to H10W 72/923 and H10W 72/952 simultaneously>
D	H01L 2224/05155	<administrative transfer to H10W 72/923 and H10W 72/952 simultaneously>
D	H01L 2224/05157	<administrative transfer to H10W 72/923 and H10W 72/952 simultaneously>
D	H01L 2224/0516	<administrative transfer to H10W 72/923 and H10W 72/952 simultaneously>
D	H01L 2224/05163	<administrative transfer to H10W 72/923 and H10W 72/952 simultaneously>
D	H01L 2224/05164	<administrative transfer to H10W 72/923 and H10W 72/952 simultaneously>
D	H01L 2224/05166	<administrative transfer to H10W 72/923 and H10W 72/952 simultaneously>
D	H01L 2224/05169	<administrative transfer to H10W 72/923 and H10W 72/952 simultaneously>
D	H01L 2224/0517	<administrative transfer to H10W 72/923 and H10W 72/952 simultaneously>
D	H01L 2224/05171	<administrative transfer to H10W 72/923 and H10W 72/952 simultaneously>
D	H01L 2224/05172	<administrative transfer to H10W 72/923 and H10W 72/952 simultaneously>
D	H01L 2224/05173	<administrative transfer to H10W 72/923 and H10W 72/952 simultaneously>
D	H01L 2224/05176	<administrative transfer to H10W 72/923 and H10W 72/952 simultaneously>
D	H01L 2224/05178	<administrative transfer to H10W 72/923 and H10W 72/952 simultaneously>
D	H01L 2224/05179	<administrative transfer to H10W 72/923 and H10W 72/952 simultaneously>
D	H01L 2224/0518	<administrative transfer to H10W 72/923 and H10W 72/952 simultaneously>
D	H01L 2224/05181	<administrative transfer to H10W 72/923 and H10W 72/952 simultaneously>
D	H01L 2224/05183	<administrative transfer to H10W 72/923 and H10W 72/952 simultaneously>
D	H01L 2224/05184	<administrative transfer to H10W 72/923 and H10W 72/952 simultaneously>
D	H01L 2224/05186	<administrative transfer to H10W 72/923 and H10W 72/952 simultaneously>
D	H01L 2224/05187	<administrative transfer to H10W 72/923 and H10W 72/952 simultaneously>
D	H01L 2224/05188	<administrative transfer to H10W 72/923 and H10W 72/952 simultaneously>
D	H01L 2224/0519	<administrative transfer to H10W 72/923 and H10W 72/952 simultaneously>
D	H01L 2224/05191	<administrative transfer to H10W 72/923 and H10W 72/953 simultaneously>
D	H01L 2224/05193	<administrative transfer to H10W 72/923 and H10W 72/953 simultaneously>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/05194	<administrative transfer to H10W 72/923 and H10W 72/953 simultaneously>
D	H01L 2224/05195	<administrative transfer to H10W 72/923 and H10W 72/953 simultaneously>
D	H01L 2224/05198	<administrative transfer to H10W 72/923 and H10W 72/925 simultaneously>
D	H01L 2224/05199	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/951 simultaneously>
D	H01L 2224/052	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05201	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05205	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05209	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05211	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05213	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05214	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05216	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05217	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05218	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/0522	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05223	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05224	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05238	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05239	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05244	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05247	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05249	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05255	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05257	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/0526	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/05263	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05264	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05266	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05269	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/0527	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05271	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05272	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05273	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05276	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05278	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05279	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/0528	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05281	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05283	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05284	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05286	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/953 simultaneously>
D	H01L 2224/05287	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/953 simultaneously>
D	H01L 2224/05288	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/953 simultaneously>
D	H01L 2224/0529	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/953 simultaneously>
D	H01L 2224/05291	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/953 simultaneously>
D	H01L 2224/05293	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/953 simultaneously>
D	H01L 2224/05294	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/953 simultaneously>
D	H01L 2224/05295	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/953 simultaneously>
D	H01L 2224/05298	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/951 simultaneously>
D	H01L 2224/05299	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/951 simultaneously>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/053	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05301	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05305	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05309	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05311	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05313	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05314	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05316	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05317	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05318	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/0532	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05323	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05324	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05338	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05339	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05344	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05347	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05349	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05355	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05357	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/0536	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05363	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05364	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05366	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05369	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/0537	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05371	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05372	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05373	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05376	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05378	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05379	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/0538	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05381	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05383	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05384	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05386	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/953 simultaneously>
D	H01L 2224/05387	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/953 simultaneously>
D	H01L 2224/05388	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/953 simultaneously>
D	H01L 2224/0539	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/953 simultaneously>
D	H01L 2224/05391	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/953 simultaneously>
D	H01L 2224/05393	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/953 simultaneously>
D	H01L 2224/05394	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/953 simultaneously>
D	H01L 2224/05395	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/953 simultaneously>
D	H01L 2224/05398	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/953 simultaneously>
D	H01L 2224/05399	<administrative transfer to H10W 72/923 and H10W 72/925 simultaneously>
D	H01L 2224/054	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05401	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05405	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05409	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/05411	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05413	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05414	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05416	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05417	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05418	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/0542	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05423	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05424	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05438	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05439	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05444	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05447	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05449	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05455	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05457	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/0546	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05463	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05464	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05466	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05469	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/0547	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05471	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05472	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05473	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/05476	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05478	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05479	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/0548	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05481	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05483	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05484	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05486	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/953 simultaneously>
D	H01L 2224/05487	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/953 simultaneously>
D	H01L 2224/05488	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/953 simultaneously>
D	H01L 2224/0549	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/953 simultaneously>
D	H01L 2224/05491	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/953 simultaneously>
D	H01L 2224/05493	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/953 simultaneously>
D	H01L 2224/05494	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/953 simultaneously>
D	H01L 2224/05495	<administrative transfer to H10W 72/923, H10W 72/925 and H10W 72/953 simultaneously>
D	H01L 2224/05498	<administrative transfer to H10W 72/923 and H10W 72/925 simultaneously>
D	H01L 2224/05499	<administrative transfer to H10W 72/923 and H10W 72/925 simultaneously>
D	H01L 2224/0554	<administrative transfer to H10W 72/923>
D	H01L 2224/05541	<administrative transfer to H10W 72/921>
D	H01L 2224/05546	<administrative transfer to H10W 72/921>
D	H01L 2224/05547	<administrative transfer to H10W 72/923>
D	H01L 2224/05548	<administrative transfer to H10W 72/922>
D	H01L 2224/0555	<administrative transfer to H10W 72/931>
D	H01L 2224/05551	<administrative transfer to H10W 72/931>
D	H01L 2224/05552	<administrative transfer to H10W 72/932>
D	H01L 2224/05553	<administrative transfer to H10W 72/932>
D	H01L 2224/05554	<administrative transfer to H10W 72/932>
D	H01L 2224/05555	<administrative transfer to H10W 72/932>
D	H01L 2224/05556	<administrative transfer to H10W 72/934>
D	H01L 2224/05557	<administrative transfer to H10W 72/934>
D	H01L 2224/05558	<administrative transfer to H10W 72/934>
D	H01L 2224/05559	<administrative transfer to H10W 72/934>
D	H01L 2224/0556	<administrative transfer to H10W 72/941>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/05561	<administrative transfer to H10W 72/942>
D	H01L 2224/05562	<administrative transfer to H10W 72/942>
D	H01L 2224/05563	<administrative transfer to H10W 72/942>
D	H01L 2224/05564	<administrative transfer to H10W 72/942>
D	H01L 2224/05565	<administrative transfer to H10W 72/942>
D	H01L 2224/05566	<administrative transfer to H10W 72/942>
D	H01L 2224/05567	<administrative transfer to H10W 72/9415>
D	H01L 2224/05568	<administrative transfer to H10W 72/9415>
D	H01L 2224/05569	<administrative transfer to H10W 72/942>
D	H01L 2224/0557	<administrative transfer to H10W 72/942>
D	H01L 2224/05571	<administrative transfer to H10W 72/9415>
D	H01L 2224/05572	<administrative transfer to H10W 72/9415>
D	H01L 2224/05573	<administrative transfer to H10W 72/90>
D	H01L 2224/05575	<administrative transfer to H10W 72/923>
D	H01L 2224/05576	<administrative transfer to H10W 72/923>
D	H01L 2224/05578	<administrative transfer to H10W 72/923>
D	H01L 2224/0558	<administrative transfer to H10W 72/923>
D	H01L 2224/05582	<administrative transfer to H10W 72/923>
D	H01L 2224/05583	<administrative transfer to H10W 72/923>
D	H01L 2224/05584	<administrative transfer to H10W 72/923>
D	H01L 2224/05599	<administrative transfer to H10W 72/951>
D	H01L 2224/056	<administrative transfer to H10W 72/952>
D	H01L 2224/05601	<administrative transfer to H10W 72/952>
D	H01L 2224/05605	<administrative transfer to H10W 72/952>
D	H01L 2224/05609	<administrative transfer to H10W 72/952>
D	H01L 2224/05611	<administrative transfer to H10W 72/952>
D	H01L 2224/05613	<administrative transfer to H10W 72/952>
D	H01L 2224/05614	<administrative transfer to H10W 72/952>
D	H01L 2224/05616	<administrative transfer to H10W 72/952>
D	H01L 2224/05617	<administrative transfer to H10W 72/952>
D	H01L 2224/05618	<administrative transfer to H10W 72/952>
D	H01L 2224/0562	<administrative transfer to H10W 72/952>
D	H01L 2224/05623	<administrative transfer to H10W 72/952>
D	H01L 2224/05624	<administrative transfer to H10W 72/952>
D	H01L 2224/05638	<administrative transfer to H10W 72/952>
D	H01L 2224/05639	<administrative transfer to H10W 72/952>
D	H01L 2224/05644	<administrative transfer to H10W 72/952>
D	H01L 2224/05647	<administrative transfer to H10W 72/952>
D	H01L 2224/05649	<administrative transfer to H10W 72/952>
D	H01L 2224/05655	<administrative transfer to H10W 72/952>
D	H01L 2224/05657	<administrative transfer to H10W 72/952>
D	H01L 2224/0566	<administrative transfer to H10W 72/952>
D	H01L 2224/05663	<administrative transfer to H10W 72/952>
D	H01L 2224/05664	<administrative transfer to H10W 72/952>
D	H01L 2224/05666	<administrative transfer to H10W 72/952>
D	H01L 2224/05669	<administrative transfer to H10W 72/952>
D	H01L 2224/0567	<administrative transfer to H10W 72/952>
D	H01L 2224/05671	<administrative transfer to H10W 72/952>
D	H01L 2224/05672	<administrative transfer to H10W 72/952>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/05673	<administrative transfer to H10W 72/952>
D	H01L 2224/05676	<administrative transfer to H10W 72/952>
D	H01L 2224/05678	<administrative transfer to H10W 72/952>
D	H01L 2224/05679	<administrative transfer to H10W 72/952>
D	H01L 2224/0568	<administrative transfer to H10W 72/952>
D	H01L 2224/05681	<administrative transfer to H10W 72/952>
D	H01L 2224/05683	<administrative transfer to H10W 72/952>
D	H01L 2224/05684	<administrative transfer to H10W 72/952>
D	H01L 2224/05686	<administrative transfer to H10W 72/953>
D	H01L 2224/05687	<administrative transfer to H10W 72/953>
D	H01L 2224/05688	<administrative transfer to H10W 72/953>
D	H01L 2224/0569	<administrative transfer to H10W 72/953>
D	H01L 2224/05691	<administrative transfer to H10W 72/953>
D	H01L 2224/05693	<administrative transfer to H10W 72/953>
D	H01L 2224/05694	<administrative transfer to H10W 72/953>
D	H01L 2224/05695	<administrative transfer to H10W 72/953>
D	H01L 2224/05698	<administrative transfer to H10W 72/925>
D	H01L 2224/05699	<administrative transfer to H10W 72/925 and H10W 72/951 simultaneously>
D	H01L 2224/057	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05701	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05705	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05709	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05711	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05713	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05714	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05716	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05717	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05718	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/0572	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05723	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05724	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05738	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05739	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/05744	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05747	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05749	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05755	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05757	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/0576	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05763	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05764	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05766	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05769	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/0577	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05771	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05772	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05773	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05776	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05778	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05779	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/0578	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05781	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05783	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05784	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05786	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>
D	H01L 2224/05787	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>
D	H01L 2224/05788	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>
D	H01L 2224/0579	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/05791	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>
D	H01L 2224/05793	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>
D	H01L 2224/05794	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>
D	H01L 2224/05795	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>
D	H01L 2224/05798	<administrative transfer to H10W 72/925>
D	H01L 2224/05799	<administrative transfer to H10W 72/925 and H10W 72/951 simultaneously>
D	H01L 2224/058	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05801	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05805	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05809	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05811	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05813	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05814	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05816	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05817	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05818	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/0582	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05823	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05824	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05838	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05839	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05844	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05847	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05849	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05855	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/05857	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/0586	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05863	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05864	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05866	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05869	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/0587	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05871	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05872	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05873	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05876	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05878	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05879	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/0588	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05881	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05883	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05884	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05886	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>
D	H01L 2224/05887	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>
D	H01L 2224/05888	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>
D	H01L 2224/0589	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>
D	H01L 2224/05891	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>
D	H01L 2224/05893	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>
D	H01L 2224/05894	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>
D	H01L 2224/05895	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/05898	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>
D	H01L 2224/05899	<administrative transfer to H10W 72/925 and H10W 72/951 simultaneously>
D	H01L 2224/059	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05901	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05905	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05909	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05911	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05913	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05914	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05916	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05917	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05918	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/0592	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05923	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05924	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05938	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05939	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05944	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05947	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05949	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05955	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05957	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/0596	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05963	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05964	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/05966	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05969	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/0597	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05971	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05972	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05973	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05976	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05978	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05979	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/0598	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05981	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05983	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05984	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/05986	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>
D	H01L 2224/05987	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>
D	H01L 2224/05988	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>
D	H01L 2224/0599	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>
D	H01L 2224/05991	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>
D	H01L 2224/05993	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>
D	H01L 2224/05994	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>
D	H01L 2224/05995	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>
D	H01L 2224/05998	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>
D	H01L 2224/05999	<administrative transfer to H10W 72/925>
D	H01L 2224/06	<administrative transfer to H10W 72/90>
D	H01L 2224/0601	<administrative transfer to H10W 72/927>
D	H01L 2224/0603	<administrative transfer to H10W 72/926>
D	H01L 2224/0605	<administrative transfer to H10W 72/936>
D	H01L 2224/06051	<administrative transfer to H10W 72/936>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/061	<administrative transfer to H10W 72/944>
D	H01L 2224/06102	<administrative transfer to H10W 72/944>
D	H01L 2224/0612	<administrative transfer to H10W 72/9445>
D	H01L 2224/0613	<administrative transfer to H10W 72/9445>
D	H01L 2224/06131	<administrative transfer to H10W 72/9445>
D	H01L 2224/06132	<administrative transfer to H10W 72/9445>
D	H01L 2224/06133	<administrative transfer to H10W 72/9445>
D	H01L 2224/06134	<administrative transfer to H10W 72/9445>
D	H01L 2224/06135	<administrative transfer to H10W 72/9445>
D	H01L 2224/06136	<administrative transfer to H10W 72/9445>
D	H01L 2224/06137	<administrative transfer to H10W 72/9445>
D	H01L 2224/06138	<administrative transfer to H10W 72/9445>
D	H01L 2224/06139	<administrative transfer to H10W 72/9445>
D	H01L 2224/0614	<administrative transfer to H10W 72/9445>
D	H01L 2224/06141	<administrative transfer to H10W 72/9445>
D	H01L 2224/06142	<administrative transfer to H10W 72/9445>
D	H01L 2224/06143	<administrative transfer to H10W 72/9445>
D	H01L 2224/06144	<administrative transfer to H10W 72/9445>
D	H01L 2224/06145	<administrative transfer to H10W 72/9445>
D	H01L 2224/06146	<administrative transfer to H10W 72/9445>
D	H01L 2224/06147	<administrative transfer to H10W 72/9445>
D	H01L 2224/06148	<administrative transfer to H10W 72/9445>
D	H01L 2224/06149	<administrative transfer to H10W 72/9445>
D	H01L 2224/0615	<administrative transfer to H10W 72/9445>
D	H01L 2224/06151	<administrative transfer to H10W 72/9445>
D	H01L 2224/06152	<administrative transfer to H10W 72/9445>
D	H01L 2224/06153	<administrative transfer to H10W 72/9445>
D	H01L 2224/06154	<administrative transfer to H10W 72/9445>
D	H01L 2224/06155	<administrative transfer to H10W 72/9445>
D	H01L 2224/06156	<administrative transfer to H10W 72/9445>
D	H01L 2224/06157	<administrative transfer to H10W 72/9445>
D	H01L 2224/06158	<administrative transfer to H10W 72/9445>
D	H01L 2224/06159	<administrative transfer to H10W 72/9445>
D	H01L 2224/0616	<administrative transfer to H10W 72/9445>
D	H01L 2224/06163	<administrative transfer to H10W 72/9445>
D	H01L 2224/06164	<administrative transfer to H10W 72/9445>
D	H01L 2224/06165	<administrative transfer to H10W 72/9445>
D	H01L 2224/06166	<administrative transfer to H10W 72/9445>
D	H01L 2224/06167	<administrative transfer to H10W 72/9445>
D	H01L 2224/06168	<administrative transfer to H10W 72/9445>
D	H01L 2224/06169	<administrative transfer to H10W 72/9445>
D	H01L 2224/06177	<administrative transfer to H10W 72/9445>
D	H01L 2224/06179	<administrative transfer to H10W 72/9445>
D	H01L 2224/0618	<administrative transfer to H10W 72/944>
D	H01L 2224/06181	<administrative transfer to H10W 72/944>
D	H01L 2224/06182	<administrative transfer to H10W 72/944>
D	H01L 2224/06183	<administrative transfer to H10W 72/944>
D	H01L 2224/06187	<administrative transfer to H10W 72/944>
D	H01L 2224/06188	<administrative transfer to H10W 72/944>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/06189	<administrative transfer to H10W 72/944>
D	H01L 2224/065	<administrative transfer to H10W 72/957>
D	H01L 2224/06505	<administrative transfer to H10W 72/957>
D	H01L 2224/0651	<administrative transfer to H10W 72/967>
D	H01L 2224/06515	<administrative transfer to H10W 72/967>
D	H01L 2224/06517	<administrative transfer to H10W 72/967 and H10W 72/963 simultaneously>
D	H01L 2224/06519	<administrative transfer to H10W 72/967 and H10W 72/965 simultaneously>
D	H01L 2224/07	<administrative transfer to H10W 72/90>
D	H01L 2224/08	<administrative transfer to H10W 72/90>
D	H01L 2224/0801	<administrative transfer to H10W 80/721>
D	H01L 2224/0805	<administrative transfer to H10W 80/732>
D	H01L 2224/08052	<administrative transfer to H10W 80/732 and H10W 72/932 simultaneously>
D	H01L 2224/08053	<administrative transfer to H10W 80/732 and H10W 72/932 simultaneously>
D	H01L 2224/08054	<administrative transfer to H10W 80/732 and H10W 72/932 simultaneously>
D	H01L 2224/08055	<administrative transfer to H10W 80/732 and H10W 72/932 simultaneously>
D	H01L 2224/08056	<administrative transfer to H10W 80/732 and H10W 72/932 simultaneously>
D	H01L 2224/08057	<administrative transfer to H10W 80/732 and H10W 72/934 simultaneously>
D	H01L 2224/08058	<administrative transfer to H10W 80/732 and H10W 72/934 simultaneously>
D	H01L 2224/08059	<administrative transfer to H10W 80/732 and H10W 72/934 simultaneously>
D	H01L 2224/0807	<administrative transfer to H10W 80/732>
D	H01L 2224/081	<administrative transfer to H10W 80/743>
D	H01L 2224/08111	<administrative transfer to H10W 80/743 and H10W 72/9415 simultaneously>
D	H01L 2224/08112	<administrative transfer to H10W 80/743 and H10W 72/9415 simultaneously>
D	H01L 2224/08113	<administrative transfer to H10W 80/743 and H10W 72/9415 simultaneously>
D	H01L 2224/0812	<administrative transfer to H10W 80/701>
D	H01L 2224/08121	<administrative transfer to H10W 80/701>
D	H01L 2224/08123	<administrative transfer to H10W 80/701>
D	H01L 2224/08135	<administrative transfer to H10W 90/791>
D	H01L 2224/08137	<administrative transfer to H10W 90/792>
D	H01L 2224/08145	<administrative transfer to H10W 90/792>
D	H01L 2224/08146	<administrative transfer to H10W 90/792>
D	H01L 2224/08147	<administrative transfer to H10W 90/792>
D	H01L 2224/08148	<administrative transfer to H10W 90/792>
D	H01L 2224/08151	<administrative transfer to H10W 90/791>
D	H01L 2224/08153	<administrative transfer to H10W 90/791>
D	H01L 2224/08155	<administrative transfer to H10W 90/794>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/0816	<administrative transfer to H10W 90/794>
D	H01L 2224/08163	<administrative transfer to H10W 90/794>
D	H01L 2224/08165	<administrative transfer to H10W 90/794>
D	H01L 2224/08167	<administrative transfer to H10W 90/794>
D	H01L 2224/08168	<administrative transfer to H10W 90/794>
D	H01L 2224/08175	<administrative transfer to H10W 90/796>
D	H01L 2224/08183	<administrative transfer to H10W 90/796>
D	H01L 2224/08187	<administrative transfer to H10W 90/796>
D	H01L 2224/08188	<administrative transfer to H10W 90/796>
D	H01L 2224/08195	<administrative transfer to H10W 90/798>
D	H01L 2224/08197	<administrative transfer to H10W 90/798>
D	H01L 2224/08198	<administrative transfer to H10W 90/798>
D	H01L 2224/08221	<administrative transfer to H10W 90/791>
D	H01L 2224/08225	<administrative transfer to H10W 90/794>
D	H01L 2224/0823	<administrative transfer to H10W 90/794>
D	H01L 2224/08233	<administrative transfer to H10W 90/794>
D	H01L 2224/08235	<administrative transfer to H10W 90/794>
D	H01L 2224/08237	<administrative transfer to H10W 90/794>
D	H01L 2224/08238	<administrative transfer to H10W 90/794>
D	H01L 2224/08245	<administrative transfer to H10W 90/796>
D	H01L 2224/08253	<administrative transfer to H10W 90/796>
D	H01L 2224/08257	<administrative transfer to H10W 90/796>
D	H01L 2224/08258	<administrative transfer to H10W 90/796>
D	H01L 2224/08265	<administrative transfer to H10W 90/798>
D	H01L 2224/08267	<administrative transfer to H10W 90/798>
D	H01L 2224/08268	<administrative transfer to H10W 90/798>
D	H01L 2224/085	<administrative transfer to H10W 80/754>
D	H01L 2224/08501	<administrative transfer to H10W 80/754>
D	H01L 2224/08502	<administrative transfer to H10W 72/9524 and H10W 80/754 simultaneously>
D	H01L 2224/08503	<administrative transfer to H10W 72/9528 and H10W 80/754 simultaneously>
D	H01L 2224/08505	<administrative transfer to H10W 80/754>
D	H01L 2224/08506	<administrative transfer to H10W 72/9524 and H10W 80/754 simultaneously>
D	H01L 2224/09	<administrative transfer to H10W 72/90>
D	H01L 2224/0901	<administrative transfer to H10W 80/721 and H10W 72/927 simultaneously>
D	H01L 2224/0903	<administrative transfer to H10W 80/721 and H10W 72/926 simultaneously>
D	H01L 2224/0905	<administrative transfer to H10W 72/936 and H10W 80/732 simultaneously>
D	H01L 2224/09051	<administrative transfer to H10W 72/936 and H10W 80/732 simultaneously>
D	H01L 2224/09055	<administrative transfer to H10W 72/936 and H10W 80/732 simultaneously>
D	H01L 2224/091	<administrative transfer to H10W 72/944 and H10W 80/743 simultaneously>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/09102	<administrative transfer to H10W 72/944 and H10W 80/743 simultaneously>
D	H01L 2224/09103	<administrative transfer to H10W 72/944 and H10W 80/743 simultaneously>
D	H01L 2224/09104	<administrative transfer to H10W 72/944 and H10W 80/743 simultaneously>
D	H01L 2224/0912	<administrative transfer to H10W 72/9445 and H10W 80/743 simultaneously>
D	H01L 2224/0913	<administrative transfer to H10W 72/9445 and H10W 80/743 simultaneously>
D	H01L 2224/09132	<administrative transfer to H10W 72/9445 and H10W 80/743 simultaneously>
D	H01L 2224/09133	<administrative transfer to H10W 72/9445 and H10W 80/743 simultaneously>
D	H01L 2224/09134	<administrative transfer to H10W 72/9445 and H10W 80/743 simultaneously>
D	H01L 2224/09135	<administrative transfer to H10W 72/9445 and H10W 80/743 simultaneously>
D	H01L 2224/0914	<administrative transfer to H10W 72/9445 and H10W 80/743 simultaneously>
D	H01L 2224/09142	<administrative transfer to H10W 72/9445 and H10W 80/743 simultaneously>
D	H01L 2224/09143	<administrative transfer to H10W 72/9445 and H10W 80/743 simultaneously>
D	H01L 2224/09144	<administrative transfer to H10W 72/9445 and H10W 80/743 simultaneously>
D	H01L 2224/09145	<administrative transfer to H10W 72/9445 and H10W 80/743 simultaneously>
D	H01L 2224/0915	<administrative transfer to H10W 72/9445 and H10W 80/743 simultaneously>
D	H01L 2224/09151	<administrative transfer to H10W 72/9445 and H10W 80/743 simultaneously>
D	H01L 2224/09152	<administrative transfer to H10W 72/9445 and H10W 80/743 simultaneously>
D	H01L 2224/09153	<administrative transfer to H10W 72/9445 and H10W 80/743 simultaneously>
D	H01L 2224/09154	<administrative transfer to H10W 72/9445 and H10W 80/743 simultaneously>
D	H01L 2224/09155	<administrative transfer to H10W 72/9445 and H10W 80/743 simultaneously>
D	H01L 2224/09156	<administrative transfer to H10W 72/9445 and H10W 80/743 simultaneously>
D	H01L 2224/0916	<administrative transfer to H10W 72/9445 and H10W 80/743 simultaneously>
D	H01L 2224/09163	<administrative transfer to H10W 72/9445 and H10W 80/743 simultaneously>
D	H01L 2224/09164	<administrative transfer to H10W 72/9445 and H10W 80/743 simultaneously>
D	H01L 2224/09165	<administrative transfer to H10W 72/9445 and H10W 80/743 simultaneously>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/09177	<administrative transfer to H10W 72/9445 and H10W 80/743 simultaneously>
D	H01L 2224/09179	<administrative transfer to H10W 72/9445 and H10W 80/743 simultaneously>
D	H01L 2224/0918	<administrative transfer to H10W 72/944 and H10W 80/743 simultaneously>
D	H01L 2224/09181	<administrative transfer to H10W 72/944 and H10W 80/743 simultaneously>
D	H01L 2224/09183	<administrative transfer to H10W 72/944 and H10W 80/743 simultaneously>
D	H01L 2224/095	<administrative transfer to H10W 72/957 and H10W 80/754 simultaneously>
D	H01L 2224/09505	<administrative transfer to H10W 72/957 and H10W 80/754 simultaneously>
D	H01L 2224/0951	<administrative transfer to H10W 72/967>
D	H01L 2224/09515	<administrative transfer to H10W 72/967>
D	H01L 2224/09517	<administrative transfer to H10W 72/967 and H10W 72/963 simultaneously>
D	H01L 2224/09519	<administrative transfer to H10W 72/967 and H10W 72/965 simultaneously>
D	H01L 2224/10	<administrative transfer to H10W 72/20>
D	H01L 2224/1012	<administrative transfer to H10W 72/281>
D	H01L 2224/10122	<administrative transfer to H10W 72/281>
D	H01L 2224/10125	<administrative transfer to H10W 72/283>
D	H01L 2224/10126	<administrative transfer to H10W 72/283>
D	H01L 2224/10135	<administrative transfer to H10W 72/285>
D	H01L 2224/10145	<administrative transfer to H10W 72/287>
D	H01L 2224/10152	<administrative transfer to H10W 72/281>
D	H01L 2224/10155	<administrative transfer to H10W 72/283>
D	H01L 2224/10156	<administrative transfer to H10W 72/283>
D	H01L 2224/10165	<administrative transfer to H10W 72/285>
D	H01L 2224/10175	<administrative transfer to H10W 72/287>
D	H01L 2224/11	<administrative transfer to H10W 72/012>
D	H01L 2224/11001	<administrative transfer to H10W 72/01204>
D	H01L 2224/11002	<administrative transfer to H10W 72/01204>
D	H01L 2224/11003	<administrative transfer to H10W 72/01204>
D	H01L 2224/11005	<administrative transfer to H10W 72/01204>
D	H01L 2224/11009	<administrative transfer to H10W 72/01204>
D	H01L 2224/11011	<administrative transfer to H10W 72/01208>
D	H01L 2224/11013	<administrative transfer to H10W 72/01208>
D	H01L 2224/11015	<administrative transfer to H10W 72/01208>
D	H01L 2224/11019	<administrative transfer to H10W 72/01208>
D	H01L 2224/111	<administrative transfer to H10W 72/01212>
D	H01L 2224/1111	<administrative transfer to H10W 72/01212>
D	H01L 2224/1112	<administrative transfer to H10W 72/01212>
D	H01L 2224/113	<administrative transfer to H10W 72/01221>
D	H01L 2224/1131	<administrative transfer to H10W 72/01223>
D	H01L 2224/11312	<administrative transfer to H10W 72/01223>
D	H01L 2224/11318	<administrative transfer to H10W 72/01223>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/1132	<administrative transfer to H10W 72/01223>
D	H01L 2224/1133	<administrative transfer to H10W 72/01225>
D	H01L 2224/11332	<administrative transfer to H10W 72/01225>
D	H01L 2224/11334	<administrative transfer to H10W 72/01225>
D	H01L 2224/1134	<administrative transfer to H10W 72/01225>
D	H01L 2224/114	<administrative transfer to H10W 72/01231>
D	H01L 2224/1141	<administrative transfer to H10W 72/01233>
D	H01L 2224/11416	<administrative transfer to H10W 72/01233>
D	H01L 2224/11418	<administrative transfer to H10W 72/01233>
D	H01L 2224/1142	<administrative transfer to H10W 72/01233>
D	H01L 2224/11422	<administrative transfer to H10W 72/01233>
D	H01L 2224/11424	<administrative transfer to H10W 72/01233>
D	H01L 2224/11426	<administrative transfer to H10W 72/01233>
D	H01L 2224/11428	<administrative transfer to H10W 72/01233>
D	H01L 2224/1143	<administrative transfer to H10W 72/01236>
D	H01L 2224/11436	<administrative transfer to H10W 72/01236>
D	H01L 2224/11438	<administrative transfer to H10W 72/01236>
D	H01L 2224/1144	<administrative transfer to H10W 72/01236>
D	H01L 2224/11442	<administrative transfer to H10W 72/01236>
D	H01L 2224/11444	<administrative transfer to H10W 72/01238>
D	H01L 2224/1145	<administrative transfer to H10W 72/01238>
D	H01L 2224/11452	<administrative transfer to H10W 72/01238>
D	H01L 2224/1146	<administrative transfer to H10W 72/01235>
D	H01L 2224/11462	<administrative transfer to H10W 72/01235>
D	H01L 2224/11464	<administrative transfer to H10W 72/01235>
D	H01L 2224/11466	<administrative transfer to H10W 72/01231>
D	H01L 2224/1147	<administrative transfer to H10W 72/01255>
D	H01L 2224/11472	<administrative transfer to H10W 72/01255>
D	H01L 2224/11474	<administrative transfer to H10W 72/01255>
D	H01L 2224/1148	<administrative transfer to H10W 72/01255>
D	H01L 2224/115	<administrative transfer to H10W 72/01261>
D	H01L 2224/11502	<administrative transfer to H10W 72/01261>
D	H01L 2224/11505	<administrative transfer to H10W 72/01261>
D	H01L 2224/1151	<administrative transfer to H10W 72/01261>
D	H01L 2224/11515	<administrative transfer to H10W 72/01261>
D	H01L 2224/1152	<administrative transfer to H10W 72/01261>
D	H01L 2224/11522	<administrative transfer to H10W 72/01261>
D	H01L 2224/11524	<administrative transfer to H10W 72/01261>
D	H01L 2224/11526	<administrative transfer to H10W 72/01261>
D	H01L 2224/1155	<administrative transfer to H10W 72/01261>
D	H01L 2224/11552	<administrative transfer to H10W 72/01261>
D	H01L 2224/11554	<administrative transfer to H10W 72/01261>
D	H01L 2224/116	<administrative transfer to H10W 72/01251>
D	H01L 2224/11602	<administrative transfer to H10W 72/01251>
D	H01L 2224/1161	<administrative transfer to H10W 72/01253>
D	H01L 2224/11612	<administrative transfer to H10W 72/01253>
D	H01L 2224/11614	<administrative transfer to H10W 72/01253>
D	H01L 2224/11616	<administrative transfer to H10W 72/01251>
D	H01L 2224/11618	<administrative transfer to H10W 72/01251>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/1162	<administrative transfer to H10W 72/01255>
D	H01L 2224/11622	<administrative transfer to H10W 72/01255>
D	H01L 2224/1163	<administrative transfer to H10W 72/01251>
D	H01L 2224/11632	<administrative transfer to H10W 72/01251>
D	H01L 2224/117	<administrative transfer to H10W 72/012>
D	H01L 2224/118	<administrative transfer to H10W 72/012>
D	H01L 2224/1181	<administrative transfer to H10W 72/01271>
D	H01L 2224/1182	<administrative transfer to H10W 72/01215>
D	H01L 2224/11821	<administrative transfer to H10W 72/01215>
D	H01L 2224/11822	<administrative transfer to H10W 72/01215>
D	H01L 2224/11823	<administrative transfer to H10W 72/01215>
D	H01L 2224/11824	<administrative transfer to H10W 72/01215>
D	H01L 2224/11825	<administrative transfer to H10W 72/01215>
D	H01L 2224/11826	<administrative transfer to H10W 72/01215>
D	H01L 2224/11827	<administrative transfer to H10W 72/01215>
D	H01L 2224/1183	<administrative transfer to H10W 72/01251>
D	H01L 2224/11831	<administrative transfer to H10W 72/01251>
D	H01L 2224/1184	<administrative transfer to H10W 72/01251>
D	H01L 2224/11845	<administrative transfer to H10W 72/01251>
D	H01L 2224/11848	<administrative transfer to H10W 72/01265>
D	H01L 2224/11849	<administrative transfer to H10W 72/01257>
D	H01L 2224/119	<administrative transfer to H10W 72/012>
D	H01L 2224/11901	<administrative transfer to H10W 72/012>
D	H01L 2224/11902	<administrative transfer to H10W 72/012>
D	H01L 2224/11903	<administrative transfer to H10W 72/012>
D	H01L 2224/11906	<administrative transfer to H10W 72/012>
D	H01L 2224/1191	<administrative transfer to H10W 72/012>
D	H01L 2224/11912	<administrative transfer to H10W 72/012>
D	H01L 2224/11914	<administrative transfer to H10W 72/012>
D	H01L 2224/11916	<administrative transfer to H10W 72/012>
D	H01L 2224/12	<administrative transfer to H10W 72/20>
D	H01L 2224/12105	<administrative transfer to H10W 72/241>
D	H01L 2224/13	<administrative transfer to H10W 72/20>
D	H01L 2224/13001	<administrative transfer to H10W 72/20>
D	H01L 2224/13005	<administrative transfer to H10W 72/221>
D	H01L 2224/13006	<administrative transfer to H10W 72/221>
D	H01L 2224/13007	<administrative transfer to H10W 72/221>
D	H01L 2224/13008	<administrative transfer to H10W 72/221>
D	H01L 2224/13009	<administrative transfer to H10W 72/221>
D	H01L 2224/1301	<administrative transfer to H10W 72/231>
D	H01L 2224/13011	<administrative transfer to H10W 72/231>
D	H01L 2224/13012	<administrative transfer to H10W 72/232>
D	H01L 2224/13013	<administrative transfer to H10W 72/232>
D	H01L 2224/13014	<administrative transfer to H10W 72/232>
D	H01L 2224/13015	<administrative transfer to H10W 72/232>
D	H01L 2224/13016	<administrative transfer to H10W 72/234>
D	H01L 2224/13017	<administrative transfer to H10W 72/234>
D	H01L 2224/13018	<administrative transfer to H10W 72/234>
D	H01L 2224/13019	<administrative transfer to H10W 72/234>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/1302	<administrative transfer to H10W 72/241>
D	H01L 2224/13021	<administrative transfer to H10W 72/242>
D	H01L 2224/13022	<administrative transfer to H10W 72/242>
D	H01L 2224/13023	<administrative transfer to H10W 72/242>
D	H01L 2224/13024	<administrative transfer to H10W 72/244>
D	H01L 2224/13025	<administrative transfer to H10W 72/244>
D	H01L 2224/13026	<administrative transfer to H10W 72/244>
D	H01L 2224/13027	<administrative transfer to H10W 72/244>
D	H01L 2224/13028	<administrative transfer to H10W 72/244>
D	H01L 2224/13075	<administrative transfer to H10W 72/224>
D	H01L 2224/13076	<administrative transfer to H10W 72/224>
D	H01L 2224/13078	<administrative transfer to H10W 72/224>
D	H01L 2224/1308	<administrative transfer to H10W 72/222>
D	H01L 2224/13082	<administrative transfer to H10W 72/222>
D	H01L 2224/13083	<administrative transfer to H10W 72/222>
D	H01L 2224/13084	<administrative transfer to H10W 72/222>
D	H01L 2224/13099	<administrative transfer to H10W 72/251>
D	H01L 2224/131	<administrative transfer to H10W 72/252>
D	H01L 2224/13101	<administrative transfer to H10W 72/252>
D	H01L 2224/13105	<administrative transfer to H10W 72/252>
D	H01L 2224/13109	<administrative transfer to H10W 72/252>
D	H01L 2224/13111	<administrative transfer to H10W 72/252>
D	H01L 2224/13113	<administrative transfer to H10W 72/252>
D	H01L 2224/13114	<administrative transfer to H10W 72/252>
D	H01L 2224/13116	<administrative transfer to H10W 72/252>
D	H01L 2224/13117	<administrative transfer to H10W 72/252>
D	H01L 2224/13118	<administrative transfer to H10W 72/252>
D	H01L 2224/1312	<administrative transfer to H10W 72/252>
D	H01L 2224/13123	<administrative transfer to H10W 72/252>
D	H01L 2224/13124	<administrative transfer to H10W 72/252>
D	H01L 2224/13138	<administrative transfer to H10W 72/252>
D	H01L 2224/13139	<administrative transfer to H10W 72/252>
D	H01L 2224/13144	<administrative transfer to H10W 72/252>
D	H01L 2224/13147	<administrative transfer to H10W 72/252>
D	H01L 2224/13149	<administrative transfer to H10W 72/252>
D	H01L 2224/13155	<administrative transfer to H10W 72/252>
D	H01L 2224/13157	<administrative transfer to H10W 72/252>
D	H01L 2224/1316	<administrative transfer to H10W 72/252>
D	H01L 2224/13163	<administrative transfer to H10W 72/252>
D	H01L 2224/13164	<administrative transfer to H10W 72/252>
D	H01L 2224/13166	<administrative transfer to H10W 72/252>
D	H01L 2224/13169	<administrative transfer to H10W 72/252>
D	H01L 2224/1317	<administrative transfer to H10W 72/252>
D	H01L 2224/13171	<administrative transfer to H10W 72/252>
D	H01L 2224/13172	<administrative transfer to H10W 72/252>
D	H01L 2224/13173	<administrative transfer to H10W 72/252>
D	H01L 2224/13176	<administrative transfer to H10W 72/252>
D	H01L 2224/13178	<administrative transfer to H10W 72/252>
D	H01L 2224/13179	<administrative transfer to H10W 72/252>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/1318	<administrative transfer to H10W 72/252>
D	H01L 2224/13181	<administrative transfer to H10W 72/252>
D	H01L 2224/13183	<administrative transfer to H10W 72/252>
D	H01L 2224/13184	<administrative transfer to H10W 72/252>
D	H01L 2224/13186	<administrative transfer to H10W 72/253>
D	H01L 2224/13187	<administrative transfer to H10W 72/253>
D	H01L 2224/13188	<administrative transfer to H10W 72/253>
D	H01L 2224/1319	<administrative transfer to H10W 72/253>
D	H01L 2224/13191	<administrative transfer to H10W 72/253>
D	H01L 2224/13193	<administrative transfer to H10W 72/253>
D	H01L 2224/13194	<administrative transfer to H10W 72/253>
D	H01L 2224/13195	<administrative transfer to H10W 72/253>
D	H01L 2224/13198	<administrative transfer to H10W 72/225>
D	H01L 2224/13199	<administrative transfer to H10W 72/225>
D	H01L 2224/132	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/13201	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/13205	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/13209	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/13211	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/13213	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/13214	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/13216	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/13217	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/13218	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/1322	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/13223	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/13224	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/13238	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/13239	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/13244	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/13247	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/13249	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/13255	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/13257	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/1326	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/13263	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/13264	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/13266	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/13269	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/1327	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/13271	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/13272	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/13273	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/13276	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/13278	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/13279	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/1328	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/13281	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/13283	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/13284	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/13286	<administrative transfer to H10W 72/225 and H10W 72/253 simultaneously>
D	H01L 2224/13287	<administrative transfer to H10W 72/225 and H10W 72/253 simultaneously>
D	H01L 2224/13288	<administrative transfer to H10W 72/225 and H10W 72/253 simultaneously>
D	H01L 2224/1329	<administrative transfer to H10W 72/225 and H10W 72/253 simultaneously>
D	H01L 2224/13291	<administrative transfer to H10W 72/225 and H10W 72/253 simultaneously>
D	H01L 2224/13293	<administrative transfer to H10W 72/225 and H10W 72/253 simultaneously>
D	H01L 2224/13294	<administrative transfer to H10W 72/225 and H10W 72/253 simultaneously>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/13295	<administrative transfer to H10W 72/225 and H10W 72/253 simultaneously>
D	H01L 2224/13298	<administrative transfer to H10W 72/225>
D	H01L 2224/13299	<administrative transfer to H10W 72/225>
D	H01L 2224/133	<administrative transfer to H10W 72/225>
D	H01L 2224/13301	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/13305	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/13309	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/13311	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/13313	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/13314	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/13316	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/13317	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/13318	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/1332	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/13323	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/13324	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/13338	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/13339	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/13344	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/13347	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/13349	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/13355	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/13357	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/1336	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/13363	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/13364	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/13366	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/13369	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/1337	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/13371	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/13372	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/13373	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/13376	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/13378	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/13379	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/1338	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/13381	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/13383	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/13384	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/13386	<administrative transfer to H10W 72/225 and H10W 72/253 simultaneously>
D	H01L 2224/13387	<administrative transfer to H10W 72/225 and H10W 72/253 simultaneously>
D	H01L 2224/13388	<administrative transfer to H10W 72/225 and H10W 72/253 simultaneously>
D	H01L 2224/1339	<administrative transfer to H10W 72/225 and H10W 72/253 simultaneously>
D	H01L 2224/13391	<administrative transfer to H10W 72/225 and H10W 72/253 simultaneously>
D	H01L 2224/13393	<administrative transfer to H10W 72/225 and H10W 72/253 simultaneously>
D	H01L 2224/13394	<administrative transfer to H10W 72/225 and H10W 72/253 simultaneously>
D	H01L 2224/13395	<administrative transfer to H10W 72/225 and H10W 72/253 simultaneously>
D	H01L 2224/13398	<administrative transfer to H10W 72/225>
D	H01L 2224/13399	<administrative transfer to H10W 72/225>
D	H01L 2224/134	<administrative transfer to H10W 72/225>
D	H01L 2224/13401	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/13405	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/13409	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/13411	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/13413	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/13414	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/13416	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/13417	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/13418	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/1342	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/13423	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/13424	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/13438	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/13439	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/13444	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/13447	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/13449	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/13455	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/13457	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/1346	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/13463	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/13464	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/13466	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/13469	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/1347	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/13471	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/13472	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/13473	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/13476	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/13478	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/13479	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/1348	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/13481	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/13483	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/13484	<administrative transfer to H10W 72/225 and H10W 72/252 simultaneously>
D	H01L 2224/13486	<administrative transfer to H10W 72/225 and H10W 72/253 simultaneously>
D	H01L 2224/13487	<administrative transfer to H10W 72/225 and H10W 72/253 simultaneously>
D	H01L 2224/13488	<administrative transfer to H10W 72/225 and H10W 72/253 simultaneously>
D	H01L 2224/1349	<administrative transfer to H10W 72/225 and H10W 72/253 simultaneously>
D	H01L 2224/13491	<administrative transfer to H10W 72/225 and H10W 72/253 simultaneously>
D	H01L 2224/13493	<administrative transfer to H10W 72/225 and H10W 72/253 simultaneously>
D	H01L 2224/13494	<administrative transfer to H10W 72/225 and H10W 72/253 simultaneously>
D	H01L 2224/13495	<administrative transfer to H10W 72/225 and H10W 72/253 simultaneously>
D	H01L 2224/13498	<administrative transfer to H10W 72/225>
D	H01L 2224/13499	<administrative transfer to H10W 72/225>
D	H01L 2224/1354	<administrative transfer to H10W 72/222>
D	H01L 2224/13541	<administrative transfer to H10W 72/223>
D	H01L 2224/1355	<administrative transfer to H10W 72/235>
D	H01L 2224/13551	<administrative transfer to H10W 72/235>
D	H01L 2224/13552	<administrative transfer to H10W 72/235>
D	H01L 2224/13553	<administrative transfer to H10W 72/235>
D	H01L 2224/1356	<administrative transfer to H10W 72/245>
D	H01L 2224/13561	<administrative transfer to H10W 72/245>
D	H01L 2224/13562	<administrative transfer to H10W 72/245>
D	H01L 2224/13563	<administrative transfer to H10W 72/245>
D	H01L 2224/13564	<administrative transfer to H10W 72/245>
D	H01L 2224/13565	<administrative transfer to H10W 72/245>
D	H01L 2224/13566	<administrative transfer to H10W 72/245>
D	H01L 2224/1357	<administrative transfer to H10W 72/223>
D	H01L 2224/13575	<administrative transfer to H10W 72/223>
D	H01L 2224/13576	<administrative transfer to H10W 72/223>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/13578	<administrative transfer to H10W 72/223>
D	H01L 2224/1358	<administrative transfer to H10W 72/223>
D	H01L 2224/13582	<administrative transfer to H10W 72/223>
D	H01L 2224/13583	<administrative transfer to H10W 72/223>
D	H01L 2224/13584	<administrative transfer to H10W 72/223>
D	H01L 2224/13599	<administrative transfer to H10W 72/255>
D	H01L 2224/136	<administrative transfer to H10W 72/255>
D	H01L 2224/13601	<administrative transfer to H10W 72/255>
D	H01L 2224/13605	<administrative transfer to H10W 72/255>
D	H01L 2224/13609	<administrative transfer to H10W 72/255>
D	H01L 2224/13611	<administrative transfer to H10W 72/255>
D	H01L 2224/13613	<administrative transfer to H10W 72/255>
D	H01L 2224/13614	<administrative transfer to H10W 72/255>
D	H01L 2224/13616	<administrative transfer to H10W 72/255>
D	H01L 2224/13617	<administrative transfer to H10W 72/255>
D	H01L 2224/13618	<administrative transfer to H10W 72/255>
D	H01L 2224/1362	<administrative transfer to H10W 72/255>
D	H01L 2224/13623	<administrative transfer to H10W 72/255>
D	H01L 2224/13624	<administrative transfer to H10W 72/255>
D	H01L 2224/13638	<administrative transfer to H10W 72/255>
D	H01L 2224/13639	<administrative transfer to H10W 72/255>
D	H01L 2224/13644	<administrative transfer to H10W 72/255>
D	H01L 2224/13647	<administrative transfer to H10W 72/255>
D	H01L 2224/13649	<administrative transfer to H10W 72/255>
D	H01L 2224/13655	<administrative transfer to H10W 72/255>
D	H01L 2224/13657	<administrative transfer to H10W 72/255>
D	H01L 2224/1366	<administrative transfer to H10W 72/255>
D	H01L 2224/13663	<administrative transfer to H10W 72/255>
D	H01L 2224/13664	<administrative transfer to H10W 72/255>
D	H01L 2224/13666	<administrative transfer to H10W 72/255>
D	H01L 2224/13669	<administrative transfer to H10W 72/255>
D	H01L 2224/1367	<administrative transfer to H10W 72/255>
D	H01L 2224/13671	<administrative transfer to H10W 72/255>
D	H01L 2224/13672	<administrative transfer to H10W 72/255>
D	H01L 2224/13673	<administrative transfer to H10W 72/255>
D	H01L 2224/13676	<administrative transfer to H10W 72/255>
D	H01L 2224/13678	<administrative transfer to H10W 72/255>
D	H01L 2224/13679	<administrative transfer to H10W 72/255>
D	H01L 2224/1368	<administrative transfer to H10W 72/255>
D	H01L 2224/13681	<administrative transfer to H10W 72/255>
D	H01L 2224/13683	<administrative transfer to H10W 72/255>
D	H01L 2224/13684	<administrative transfer to H10W 72/255>
D	H01L 2224/13686	<administrative transfer to H10W 72/255>
D	H01L 2224/13687	<administrative transfer to H10W 72/255>
D	H01L 2224/13688	<administrative transfer to H10W 72/255>
D	H01L 2224/1369	<administrative transfer to H10W 72/255>
D	H01L 2224/13691	<administrative transfer to H10W 72/255>
D	H01L 2224/13693	<administrative transfer to H10W 72/255>
D	H01L 2224/13694	<administrative transfer to H10W 72/255>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/13695	<administrative transfer to H10W 72/255>
D	H01L 2224/13698	<administrative transfer to H10W 72/255>
D	H01L 2224/13699	<administrative transfer to H10W 72/255>
D	H01L 2224/137	<administrative transfer to H10W 72/255>
D	H01L 2224/13701	<administrative transfer to H10W 72/255>
D	H01L 2224/13705	<administrative transfer to H10W 72/255>
D	H01L 2224/13709	<administrative transfer to H10W 72/255>
D	H01L 2224/13711	<administrative transfer to H10W 72/255>
D	H01L 2224/13713	<administrative transfer to H10W 72/255>
D	H01L 2224/13714	<administrative transfer to H10W 72/255>
D	H01L 2224/13716	<administrative transfer to H10W 72/255>
D	H01L 2224/13717	<administrative transfer to H10W 72/255>
D	H01L 2224/13718	<administrative transfer to H10W 72/255>
D	H01L 2224/1372	<administrative transfer to H10W 72/255>
D	H01L 2224/13723	<administrative transfer to H10W 72/255>
D	H01L 2224/13724	<administrative transfer to H10W 72/255>
D	H01L 2224/13738	<administrative transfer to H10W 72/255>
D	H01L 2224/13739	<administrative transfer to H10W 72/255>
D	H01L 2224/13744	<administrative transfer to H10W 72/255>
D	H01L 2224/13747	<administrative transfer to H10W 72/255>
D	H01L 2224/13749	<administrative transfer to H10W 72/255>
D	H01L 2224/13755	<administrative transfer to H10W 72/255>
D	H01L 2224/13757	<administrative transfer to H10W 72/255>
D	H01L 2224/1376	<administrative transfer to H10W 72/255>
D	H01L 2224/13763	<administrative transfer to H10W 72/255>
D	H01L 2224/13764	<administrative transfer to H10W 72/255>
D	H01L 2224/13766	<administrative transfer to H10W 72/255>
D	H01L 2224/13769	<administrative transfer to H10W 72/255>
D	H01L 2224/1377	<administrative transfer to H10W 72/255>
D	H01L 2224/13771	<administrative transfer to H10W 72/255>
D	H01L 2224/13772	<administrative transfer to H10W 72/255>
D	H01L 2224/13773	<administrative transfer to H10W 72/255>
D	H01L 2224/13776	<administrative transfer to H10W 72/255>
D	H01L 2224/13778	<administrative transfer to H10W 72/255>
D	H01L 2224/13779	<administrative transfer to H10W 72/255>
D	H01L 2224/1378	<administrative transfer to H10W 72/255>
D	H01L 2224/13781	<administrative transfer to H10W 72/255>
D	H01L 2224/13783	<administrative transfer to H10W 72/255>
D	H01L 2224/13784	<administrative transfer to H10W 72/255>
D	H01L 2224/13786	<administrative transfer to H10W 72/255>
D	H01L 2224/13787	<administrative transfer to H10W 72/255>
D	H01L 2224/13788	<administrative transfer to H10W 72/255>
D	H01L 2224/1379	<administrative transfer to H10W 72/255>
D	H01L 2224/13791	<administrative transfer to H10W 72/255>
D	H01L 2224/13793	<administrative transfer to H10W 72/255>
D	H01L 2224/13794	<administrative transfer to H10W 72/255>
D	H01L 2224/13795	<administrative transfer to H10W 72/255>
D	H01L 2224/13798	<administrative transfer to H10W 72/255>
D	H01L 2224/13799	<administrative transfer to H10W 72/255>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/138	<administrative transfer to H10W 72/255>
D	H01L 2224/13801	<administrative transfer to H10W 72/255>
D	H01L 2224/13805	<administrative transfer to H10W 72/255>
D	H01L 2224/13809	<administrative transfer to H10W 72/255>
D	H01L 2224/13811	<administrative transfer to H10W 72/255>
D	H01L 2224/13813	<administrative transfer to H10W 72/255>
D	H01L 2224/13814	<administrative transfer to H10W 72/255>
D	H01L 2224/13816	<administrative transfer to H10W 72/255>
D	H01L 2224/13817	<administrative transfer to H10W 72/255>
D	H01L 2224/13818	<administrative transfer to H10W 72/255>
D	H01L 2224/1382	<administrative transfer to H10W 72/255>
D	H01L 2224/13823	<administrative transfer to H10W 72/255>
D	H01L 2224/13824	<administrative transfer to H10W 72/255>
D	H01L 2224/13838	<administrative transfer to H10W 72/255>
D	H01L 2224/13839	<administrative transfer to H10W 72/255>
D	H01L 2224/13844	<administrative transfer to H10W 72/255>
D	H01L 2224/13847	<administrative transfer to H10W 72/255>
D	H01L 2224/13849	<administrative transfer to H10W 72/255>
D	H01L 2224/13855	<administrative transfer to H10W 72/255>
D	H01L 2224/13857	<administrative transfer to H10W 72/255>
D	H01L 2224/1386	<administrative transfer to H10W 72/255>
D	H01L 2224/13863	<administrative transfer to H10W 72/255>
D	H01L 2224/13864	<administrative transfer to H10W 72/255>
D	H01L 2224/13866	<administrative transfer to H10W 72/255>
D	H01L 2224/13869	<administrative transfer to H10W 72/255>
D	H01L 2224/1387	<administrative transfer to H10W 72/255>
D	H01L 2224/13871	<administrative transfer to H10W 72/255>
D	H01L 2224/13872	<administrative transfer to H10W 72/255>
D	H01L 2224/13873	<administrative transfer to H10W 72/255>
D	H01L 2224/13876	<administrative transfer to H10W 72/255>
D	H01L 2224/13878	<administrative transfer to H10W 72/255>
D	H01L 2224/13879	<administrative transfer to H10W 72/255>
D	H01L 2224/1388	<administrative transfer to H10W 72/255>
D	H01L 2224/13881	<administrative transfer to H10W 72/255>
D	H01L 2224/13883	<administrative transfer to H10W 72/255>
D	H01L 2224/13884	<administrative transfer to H10W 72/255>
D	H01L 2224/13886	<administrative transfer to H10W 72/255>
D	H01L 2224/13887	<administrative transfer to H10W 72/255>
D	H01L 2224/13888	<administrative transfer to H10W 72/255>
D	H01L 2224/1389	<administrative transfer to H10W 72/255>
D	H01L 2224/13891	<administrative transfer to H10W 72/255>
D	H01L 2224/13893	<administrative transfer to H10W 72/255>
D	H01L 2224/13894	<administrative transfer to H10W 72/255>
D	H01L 2224/13895	<administrative transfer to H10W 72/255>
D	H01L 2224/13898	<administrative transfer to H10W 72/255>
D	H01L 2224/13899	<administrative transfer to H10W 72/255>
D	H01L 2224/139	<administrative transfer to H10W 72/255>
D	H01L 2224/13901	<administrative transfer to H10W 72/255>
D	H01L 2224/13905	<administrative transfer to H10W 72/255>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/13909	<administrative transfer to H10W 72/255>
D	H01L 2224/13911	<administrative transfer to H10W 72/255>
D	H01L 2224/13913	<administrative transfer to H10W 72/255>
D	H01L 2224/13914	<administrative transfer to H10W 72/255>
D	H01L 2224/13916	<administrative transfer to H10W 72/255>
D	H01L 2224/13917	<administrative transfer to H10W 72/255>
D	H01L 2224/13918	<administrative transfer to H10W 72/255>
D	H01L 2224/1392	<administrative transfer to H10W 72/255>
D	H01L 2224/13923	<administrative transfer to H10W 72/255>
D	H01L 2224/13924	<administrative transfer to H10W 72/255>
D	H01L 2224/13938	<administrative transfer to H10W 72/255>
D	H01L 2224/13939	<administrative transfer to H10W 72/255>
D	H01L 2224/13944	<administrative transfer to H10W 72/255>
D	H01L 2224/13947	<administrative transfer to H10W 72/255>
D	H01L 2224/13949	<administrative transfer to H10W 72/255>
D	H01L 2224/13955	<administrative transfer to H10W 72/255>
D	H01L 2224/13957	<administrative transfer to H10W 72/255>
D	H01L 2224/1396	<administrative transfer to H10W 72/255>
D	H01L 2224/13963	<administrative transfer to H10W 72/255>
D	H01L 2224/13964	<administrative transfer to H10W 72/255>
D	H01L 2224/13966	<administrative transfer to H10W 72/255>
D	H01L 2224/13969	<administrative transfer to H10W 72/255>
D	H01L 2224/1397	<administrative transfer to H10W 72/255>
D	H01L 2224/13971	<administrative transfer to H10W 72/255>
D	H01L 2224/13972	<administrative transfer to H10W 72/255>
D	H01L 2224/13973	<administrative transfer to H10W 72/255>
D	H01L 2224/13976	<administrative transfer to H10W 72/255>
D	H01L 2224/13978	<administrative transfer to H10W 72/255>
D	H01L 2224/13979	<administrative transfer to H10W 72/255>
D	H01L 2224/1398	<administrative transfer to H10W 72/255>
D	H01L 2224/13981	<administrative transfer to H10W 72/255>
D	H01L 2224/13983	<administrative transfer to H10W 72/255>
D	H01L 2224/13984	<administrative transfer to H10W 72/255>
D	H01L 2224/13986	<administrative transfer to H10W 72/255>
D	H01L 2224/13987	<administrative transfer to H10W 72/255>
D	H01L 2224/13988	<administrative transfer to H10W 72/255>
D	H01L 2224/1399	<administrative transfer to H10W 72/255>
D	H01L 2224/13991	<administrative transfer to H10W 72/255>
D	H01L 2224/13993	<administrative transfer to H10W 72/255>
D	H01L 2224/13994	<administrative transfer to H10W 72/255>
D	H01L 2224/13995	<administrative transfer to H10W 72/255>
D	H01L 2224/13998	<administrative transfer to H10W 72/255>
D	H01L 2224/13999	<administrative transfer to H10W 72/255>
D	H01L 2224/14	<administrative transfer to H10W 72/20>
D	H01L 2224/1401	<administrative transfer to H10W 72/228>
D	H01L 2224/1403	<administrative transfer to H10W 72/227>
D	H01L 2224/1405	<administrative transfer to H10W 72/231>
D	H01L 2224/14051	<administrative transfer to H10W 72/237>
D	H01L 2224/141	<administrative transfer to H10W 72/247>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/14104	<administrative transfer to H10W 72/244 and H10W 72/247 simultaneously>
D	H01L 2224/1411	<administrative transfer to H10W 72/244 and H10W 72/247 simultaneously>
D	H01L 2224/1412	<administrative transfer to H10W 72/248>
D	H01L 2224/1413	<administrative transfer to H10W 72/248>
D	H01L 2224/14131	<administrative transfer to H10W 72/248>
D	H01L 2224/14132	<administrative transfer to H10W 72/248>
D	H01L 2224/14133	<administrative transfer to H10W 72/248>
D	H01L 2224/14134	<administrative transfer to H10W 72/248>
D	H01L 2224/14135	<administrative transfer to H10W 72/248>
D	H01L 2224/14136	<administrative transfer to H10W 72/248>
D	H01L 2224/1414	<administrative transfer to H10W 72/248>
D	H01L 2224/14141	<administrative transfer to H10W 72/248>
D	H01L 2224/14142	<administrative transfer to H10W 72/248>
D	H01L 2224/14143	<administrative transfer to H10W 72/248>
D	H01L 2224/14144	<administrative transfer to H10W 72/248>
D	H01L 2224/14145	<administrative transfer to H10W 72/248>
D	H01L 2224/14146	<administrative transfer to H10W 72/248>
D	H01L 2224/1415	<administrative transfer to H10W 72/248>
D	H01L 2224/14151	<administrative transfer to H10W 72/248>
D	H01L 2224/14152	<administrative transfer to H10W 72/248>
D	H01L 2224/14153	<administrative transfer to H10W 72/248>
D	H01L 2224/14154	<administrative transfer to H10W 72/248>
D	H01L 2224/14155	<administrative transfer to H10W 72/248>
D	H01L 2224/14156	<administrative transfer to H10W 72/248>
D	H01L 2224/1416	<administrative transfer to H10W 72/248>
D	H01L 2224/14163	<administrative transfer to H10W 72/248>
D	H01L 2224/14164	<administrative transfer to H10W 72/248>
D	H01L 2224/14165	<administrative transfer to H10W 72/248>
D	H01L 2224/14166	<administrative transfer to H10W 72/248>
D	H01L 2224/14177	<administrative transfer to H10W 72/248>
D	H01L 2224/14179	<administrative transfer to H10W 72/248>
D	H01L 2224/1418	<administrative transfer to H10W 72/248>
D	H01L 2224/14181	<administrative transfer to H10W 72/248>
D	H01L 2224/14183	<administrative transfer to H10W 72/248>
D	H01L 2224/145	<administrative transfer to H10W 72/248>
D	H01L 2224/14505	<administrative transfer to H10W 72/257>
D	H01L 2224/1451	<administrative transfer to H10W 72/261>
D	H01L 2224/14515	<administrative transfer to H10W 72/267>
D	H01L 2224/14517	<administrative transfer to H10W 72/267 and H10W 72/263 simultaneously>
D	H01L 2224/14519	<administrative transfer to H10W 72/267 and H10W 72/265 simultaneously>
D	H01L 2224/15	<administrative transfer to H10W 72/07251 and H10W 72/20 simultaneously>
D	H01L 2224/16	<administrative transfer to H10W 72/07251 and H10W 72/20 simultaneously>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/1601	<administrative transfer to H10W 72/07252 and H10W 72/221 simultaneously>
D	H01L 2224/16012	<administrative transfer to H10W 72/07252 and H10W 72/221 simultaneously>
D	H01L 2224/16013	<administrative transfer to H10W 72/07252 and H10W 72/221 simultaneously>
D	H01L 2224/16014	<administrative transfer to H10W 72/07252 and H10W 72/221 simultaneously>
D	H01L 2224/1605	<administrative transfer to H10W 72/07253 and H10W 72/231 simultaneously>
D	H01L 2224/16052	<administrative transfer to H10W 72/07253 and H10W 72/232 simultaneously>
D	H01L 2224/16054	<administrative transfer to H10W 72/07253 and H10W 72/232 simultaneously>
D	H01L 2224/16055	<administrative transfer to H10W 72/07253 and H10W 72/232 simultaneously>
D	H01L 2224/16056	<administrative transfer to H10W 72/07253 and H10W 72/232 simultaneously>
D	H01L 2224/16057	<administrative transfer to H10W 72/07253 and H10W 72/234 simultaneously>
D	H01L 2224/16058	<administrative transfer to H10W 72/07253 and H10W 72/234 simultaneously>
D	H01L 2224/16059	<administrative transfer to H10W 72/07253 and H10W 72/234 simultaneously>
D	H01L 2224/1607	<administrative transfer to H10W 72/07253 and H10W 72/234 simultaneously>
D	H01L 2224/161	<administrative transfer to H10W 72/07254 and H10W 72/241 simultaneously>
D	H01L 2224/16104	<administrative transfer to H10W 72/07254 and H10W 72/244 simultaneously>
D	H01L 2224/16105	<administrative transfer to H10W 72/07254 and H10W 72/244 simultaneously>
D	H01L 2224/16106	<administrative transfer to H10W 72/07254 and H10W 72/244 simultaneously>
D	H01L 2224/16108	<administrative transfer to H10W 72/07254 and H10W 72/242 simultaneously>
D	H01L 2224/16111	<administrative transfer to H10W 72/07254 and H10W 72/242 simultaneously>
D	H01L 2224/16112	<administrative transfer to H10W 72/07254 and H10W 72/242 simultaneously>
D	H01L 2224/16113	<administrative transfer to H10W 72/07254 and H10W 72/242 simultaneously>
D	H01L 2224/1613	<administrative transfer to H10W 72/07254 and H10W 72/242 simultaneously>
D	H01L 2224/16135	<administrative transfer to H10W 90/721>
D	H01L 2224/16137	<administrative transfer to H10W 90/723>
D	H01L 2224/16141	<administrative transfer to H10W 90/721>
D	H01L 2224/16145	<administrative transfer to H10W 90/722>
D	H01L 2224/16146	<administrative transfer to H10W 90/722>
D	H01L 2224/16147	<administrative transfer to H10W 90/722>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/16148	<administrative transfer to H10W 90/722>
D	H01L 2224/16151	<administrative transfer to H10W 90/721>
D	H01L 2224/16153	<administrative transfer to H10W 90/721>
D	H01L 2224/16155	<administrative transfer to H10W 90/725>
D	H01L 2224/16157	<administrative transfer to H10W 90/725>
D	H01L 2224/1616	<administrative transfer to H10W 90/725>
D	H01L 2224/16163	<administrative transfer to H10W 90/725>
D	H01L 2224/16165	<administrative transfer to H10W 90/725>
D	H01L 2224/16167	<administrative transfer to H10W 90/725>
D	H01L 2224/16168	<administrative transfer to H10W 90/725>
D	H01L 2224/16175	<administrative transfer to H10W 90/727>
D	H01L 2224/16183	<administrative transfer to H10W 90/727>
D	H01L 2224/16187	<administrative transfer to H10W 90/727>
D	H01L 2224/16188	<administrative transfer to H10W 90/727>
D	H01L 2224/16195	<administrative transfer to H10W 90/729>
D	H01L 2224/16197	<administrative transfer to H10W 90/729>
D	H01L 2224/16198	<administrative transfer to H10W 90/729>
D	H01L 2224/16221	<administrative transfer to H10W 90/721>
D	H01L 2224/16225	<administrative transfer to H10W 90/724>
D	H01L 2224/16227	<administrative transfer to H10W 90/724>
D	H01L 2224/1623	<administrative transfer to H10W 90/724>
D	H01L 2224/16233	<administrative transfer to H10W 90/724>
D	H01L 2224/16235	<administrative transfer to H10W 90/724>
D	H01L 2224/16237	<administrative transfer to H10W 90/724>
D	H01L 2224/16238	<administrative transfer to H10W 90/724>
D	H01L 2224/1624	<administrative transfer to H10W 90/724>
D	H01L 2224/16245	<administrative transfer to H10W 90/726>
D	H01L 2224/16253	<administrative transfer to H10W 90/726>
D	H01L 2224/16257	<administrative transfer to H10W 90/726>
D	H01L 2224/16258	<administrative transfer to H10W 90/726>
D	H01L 2224/1626	<administrative transfer to H10W 90/726>
D	H01L 2224/16265	<administrative transfer to H10W 90/728>
D	H01L 2224/16267	<administrative transfer to H10W 90/728>
D	H01L 2224/16268	<administrative transfer to H10W 90/728>
D	H01L 2224/165	<administrative transfer to H10W 72/07255 and H10W 72/251 simultaneously>
D	H01L 2224/16501	<administrative transfer to H10W 72/07255 and H10W 72/251 simultaneously>
D	H01L 2224/16502	<administrative transfer to H10W 72/07255 and H10W 72/2524 simultaneously>
D	H01L 2224/16503	<administrative transfer to H10W 72/07255 and H10W 72/2528 simultaneously>
D	H01L 2224/16505	<administrative transfer to H10W 72/07255 and H10W 72/251 simultaneously>
D	H01L 2224/16506	<administrative transfer to H10W 72/07255 and H10W 72/2524 simultaneously>
D	H01L 2224/16507	<administrative transfer to H10W 72/07255 and H10W 72/2528 simultaneously>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/17	<administrative transfer to H10W 72/07251 and H10W 72/20 simultaneously>
D	H01L 2224/1701	<administrative transfer to H10W 72/07252 and H10W 72/228 simultaneously>
D	H01L 2224/1703	<administrative transfer to H10W 72/07252 and H10W 72/227 simultaneously>
D	H01L 2224/1705	<administrative transfer to H10W 72/231 and H10W 72/07253 simultaneously>
D	H01L 2224/17051	<administrative transfer to H10W 72/237 and H10W 72/07253 simultaneously>
D	H01L 2224/17055	<administrative transfer to H10W 72/237 and H10W 72/07253 simultaneously>
D	H01L 2224/171	<administrative transfer to H10W 72/07254 and H10W 72/247 simultaneously>
D	H01L 2224/17104	<administrative transfer to H10W 72/07254, H10W 72/244 and H10W 72/247 simultaneously>
D	H01L 2224/17106	<administrative transfer to H10W 72/07254, H10W 72/244 and H10W 72/247 simultaneously>
D	H01L 2224/17107	<administrative transfer to H10W 72/07254, H10W 72/244 and H10W 72/247 simultaneously>
D	H01L 2224/1712	<administrative transfer to H10W 72/07254 and H10W 72/248 simultaneously>
D	H01L 2224/1713	<administrative transfer to H10W 72/07254 and H10W 72/248 simultaneously>
D	H01L 2224/17132	<administrative transfer to H10W 72/07254 and H10W 72/248 simultaneously>
D	H01L 2224/17133	<administrative transfer to H10W 72/07254 and H10W 72/248 simultaneously>
D	H01L 2224/17134	<administrative transfer to H10W 72/07254 and H10W 72/248 simultaneously>
D	H01L 2224/17135	<administrative transfer to H10W 72/07254 and H10W 72/248 simultaneously>
D	H01L 2224/17136	<administrative transfer to H10W 72/07254 and H10W 72/248 simultaneously>
D	H01L 2224/1714	<administrative transfer to H10W 72/07254 and H10W 72/248 simultaneously>
D	H01L 2224/17142	<administrative transfer to H10W 72/07254 and H10W 72/248 simultaneously>
D	H01L 2224/17143	<administrative transfer to H10W 72/07254 and H10W 72/248 simultaneously>
D	H01L 2224/17144	<administrative transfer to H10W 72/07254 and H10W 72/248 simultaneously>
D	H01L 2224/17145	<administrative transfer to H10W 72/07254 and H10W 72/248 simultaneously>
D	H01L 2224/17146	<administrative transfer to H10W 72/07254 and H10W 72/248 simultaneously>
D	H01L 2224/1715	<administrative transfer to H10W 72/07254 and H10W 72/248 simultaneously>
D	H01L 2224/17151	<administrative transfer to H10W 72/07254 and H10W 72/248 simultaneously>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/17152	<administrative transfer to H10W 72/07254 and H10W 72/248 simultaneously>
D	H01L 2224/17153	<administrative transfer to H10W 72/07254 and H10W 72/248 simultaneously>
D	H01L 2224/17154	<administrative transfer to H10W 72/07254 and H10W 72/248 simultaneously>
D	H01L 2224/17155	<administrative transfer to H10W 72/07254 and H10W 72/248 simultaneously>
D	H01L 2224/17156	<administrative transfer to H10W 72/07254 and H10W 72/248 simultaneously>
D	H01L 2224/1716	<administrative transfer to H10W 72/07254 and H10W 72/248 simultaneously>
D	H01L 2224/17163	<administrative transfer to H10W 72/07254 and H10W 72/248 simultaneously>
D	H01L 2224/17164	<administrative transfer to H10W 72/07254 and H10W 72/248 simultaneously>
D	H01L 2224/17165	<administrative transfer to H10W 72/07254 and H10W 72/248 simultaneously>
D	H01L 2224/17166	<administrative transfer to H10W 72/07254 and H10W 72/248 simultaneously>
D	H01L 2224/17177	<administrative transfer to H10W 72/07254 and H10W 72/248 simultaneously>
D	H01L 2224/17179	<administrative transfer to H10W 72/07254 and H10W 72/248 simultaneously>
D	H01L 2224/1718	<administrative transfer to H10W 72/07254 and H10W 72/247 simultaneously>
D	H01L 2224/17181	<administrative transfer to H10W 72/07254 and H10W 72/247 simultaneously>
D	H01L 2224/17183	<administrative transfer to H10W 72/07254 and H10W 72/247 simultaneously>
D	H01L 2224/175	<administrative transfer to H10W 72/07255 and H10W 72/257 simultaneously>
D	H01L 2224/17505	<administrative transfer to H10W 72/07255 and H10W 72/257 simultaneously>
D	H01L 2224/1751	<administrative transfer to H10W 72/261>
D	H01L 2224/17515	<administrative transfer to H10W 72/267>
D	H01L 2224/17517	<administrative transfer to H10W 72/267 and H10W 72/263 simultaneously>
D	H01L 2224/17519	<administrative transfer to H10W 72/267 and H10W 72/265 simultaneously>
D	H01L 2224/18	<administrative transfer to H10W 70/60>
D	H01L 2224/19	<administrative transfer to H10W 70/09>
D	H01L 2224/20	<administrative transfer to H10W 70/60>
D	H01L 2224/21	<administrative transfer to H10W 70/60>
D	H01L 2224/2101	<administrative transfer to H10W 70/60>
D	H01L 2224/2105	<administrative transfer to H10W 70/60>
D	H01L 2224/211	<administrative transfer to H10W 70/60>
D	H01L 2224/214	<administrative transfer to H10W 70/6528>
D	H01L 2224/215	<administrative transfer to H10W 70/60>
D	H01L 2224/22	<administrative transfer to H10W 70/60>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/2201	<administrative transfer to H10W 70/60>
D	H01L 2224/2205	<administrative transfer to H10W 70/60>
D	H01L 2224/221	<administrative transfer to H10W 70/60>
D	H01L 2224/224	<administrative transfer to H10W 70/6528>
D	H01L 2224/225	<administrative transfer to H10W 70/60>
D	H01L 2224/22505	<administrative transfer to H10W 70/60>
D	H01L 2224/23	<administrative transfer to H10W 70/60>
D	H01L 2224/24	<administrative transfer to H10W 70/60>
D	H01L 2224/2401	<administrative transfer to H10W 70/60>
D	H01L 2224/24011	<administrative transfer to H10W 70/60>
D	H01L 2224/2402	<administrative transfer to H10W 70/60>
D	H01L 2224/2405	<administrative transfer to H10W 70/60>
D	H01L 2224/24051	<administrative transfer to H10W 70/60>
D	H01L 2224/241	<administrative transfer to H10W 70/60>
D	H01L 2224/24101	<administrative transfer to H10W 70/60>
D	H01L 2224/24105	<administrative transfer to H10W 70/6523>
D	H01L 2224/2413	<administrative transfer to H10W 70/60>
D	H01L 2224/24135	<administrative transfer to H10W 90/00>
D	H01L 2224/24137	<administrative transfer to H10W 90/10>
D	H01L 2224/24141	<administrative transfer to H10W 90/20>
D	H01L 2224/24145	<administrative transfer to H10W 90/22>
D	H01L 2224/24146	<administrative transfer to H10W 90/22>
D	H01L 2224/24147	<administrative transfer to H10W 90/22>
D	H01L 2224/24151	<administrative transfer to H10W 90/00>
D	H01L 2224/24153	<administrative transfer to H10W 90/00>
D	H01L 2224/24155	<administrative transfer to H10W 90/00>
D	H01L 2224/24175	<administrative transfer to H10W 90/00>
D	H01L 2224/24195	<administrative transfer to H10W 90/00>
D	H01L 2224/24221	<administrative transfer to H10W 90/00>
D	H01L 2224/24225	<administrative transfer to H10W 90/00>
D	H01L 2224/24226	<administrative transfer to H10W 90/00>
D	H01L 2224/24227	<administrative transfer to H10W 90/00>
D	H01L 2224/24245	<administrative transfer to H10W 90/00>
D	H01L 2224/24246	<administrative transfer to H10W 90/00>
D	H01L 2224/24247	<administrative transfer to H10W 90/00>
D	H01L 2224/24265	<administrative transfer to H10W 90/00>
D	H01L 2224/244	<administrative transfer to H10W 70/6528>
D	H01L 2224/245	<administrative transfer to H10W 70/60>
D	H01L 2224/2499	<administrative transfer to H10W 70/60>
D	H01L 2224/24991	<administrative transfer to H10W 70/60>
D	H01L 2224/24992	<administrative transfer to H10W 70/60>
D	H01L 2224/24996	<administrative transfer to H10W 70/60>
D	H01L 2224/24997	<administrative transfer to H10W 70/60>
D	H01L 2224/24998	<administrative transfer to H10W 70/60>
D	H01L 2224/25	<administrative transfer to H10W 70/60>
D	H01L 2224/2501	<administrative transfer to H10W 70/60>
D	H01L 2224/2505	<administrative transfer to H10W 70/60>
D	H01L 2224/251	<administrative transfer to H10W 70/60>
D	H01L 2224/25105	<administrative transfer to H10W 70/6523>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/2511	<administrative transfer to H10W 70/60>
D	H01L 2224/25111	<administrative transfer to H10W 70/60>
D	H01L 2224/25112	<administrative transfer to H10W 70/60>
D	H01L 2224/25113	<administrative transfer to H10W 70/60>
D	H01L 2224/2512	<administrative transfer to H10W 70/654>
D	H01L 2224/25171	<administrative transfer to H10W 70/655>
D	H01L 2224/25174	<administrative transfer to H10W 70/654>
D	H01L 2224/25175	<administrative transfer to H10W 70/654>
D	H01L 2224/25177	<administrative transfer to H10W 70/654>
D	H01L 2224/2518	<administrative transfer to H10W 70/60>
D	H01L 2224/254	<administrative transfer to H10W 70/6528>
D	H01L 2224/2541	<administrative transfer to H10W 70/6528>
D	H01L 2224/2543	<administrative transfer to H10W 70/6528>
D	H01L 2224/255	<administrative transfer to H10W 70/65>
D	H01L 2224/26	<administrative transfer to H10W 72/30>
D	H01L 2224/2612	<administrative transfer to H10W 72/381>
D	H01L 2224/26122	<administrative transfer to H10W 72/381>
D	H01L 2224/26125	<administrative transfer to H10W 72/383>
D	H01L 2224/26135	<administrative transfer to H10W 72/385>
D	H01L 2224/26145	<administrative transfer to H10W 72/387>
D	H01L 2224/26152	<administrative transfer to H10W 72/381>
D	H01L 2224/26155	<administrative transfer to H10W 72/383>
D	H01L 2224/26165	<administrative transfer to H10W 72/385>
D	H01L 2224/26175	<administrative transfer to H10W 72/387>
D	H01L 2224/27	<administrative transfer to H10W 72/013>
D	H01L 2224/27001	<administrative transfer to H10W 72/01304>
D	H01L 2224/27002	<administrative transfer to H10W 72/01304>
D	H01L 2224/27003	<administrative transfer to H10W 72/01304>
D	H01L 2224/27005	<administrative transfer to H10W 72/01304>
D	H01L 2224/27009	<administrative transfer to H10W 72/01304>
D	H01L 2224/27011	<administrative transfer to H10W 72/01308>
D	H01L 2224/27013	<administrative transfer to H10W 72/01308>
D	H01L 2224/27015	<administrative transfer to H10W 72/01308>
D	H01L 2224/27019	<administrative transfer to H10W 72/01308>
D	H01L 2224/271	<administrative transfer to H10W 72/013>
D	H01L 2224/2711	<administrative transfer to H10W 72/01351>
D	H01L 2224/2712	<administrative transfer to H10W 72/01315>
D	H01L 2224/273	<administrative transfer to H10W 72/01321>
D	H01L 2224/2731	<administrative transfer to H10W 72/01323>
D	H01L 2224/27312	<administrative transfer to H10W 72/01323>
D	H01L 2224/27318	<administrative transfer to H10W 72/01323>
D	H01L 2224/2732	<administrative transfer to H10W 72/01323>
D	H01L 2224/2733	<administrative transfer to H10W 72/01325>
D	H01L 2224/27332	<administrative transfer to H10W 72/01325>
D	H01L 2224/27334	<administrative transfer to H10W 72/01325>
D	H01L 2224/274	<administrative transfer to H10W 72/01331>
D	H01L 2224/2741	<administrative transfer to H10W 72/01333>
D	H01L 2224/27416	<administrative transfer to H10W 72/01333>
D	H01L 2224/27418	<administrative transfer to H10W 72/01333>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/2742	<administrative transfer to H10W 72/01333>
D	H01L 2224/27422	<administrative transfer to H10W 72/01333>
D	H01L 2224/27424	<administrative transfer to H10W 72/01333>
D	H01L 2224/27426	<administrative transfer to H10W 72/01333>
D	H01L 2224/27428	<administrative transfer to H10W 72/01333>
D	H01L 2224/2743	<administrative transfer to H10W 72/01336>
D	H01L 2224/27436	<administrative transfer to H10W 72/01336>
D	H01L 2224/27438	<administrative transfer to H10W 72/01336>
D	H01L 2224/2744	<administrative transfer to H10W 72/01336>
D	H01L 2224/27442	<administrative transfer to H10W 72/01336>
D	H01L 2224/27444	<administrative transfer to H10W 72/01338>
D	H01L 2224/2745	<administrative transfer to H10W 72/01338>
D	H01L 2224/27452	<administrative transfer to H10W 72/01338>
D	H01L 2224/2746	<administrative transfer to H10W 72/01335>
D	H01L 2224/27462	<administrative transfer to H10W 72/01335>
D	H01L 2224/27464	<administrative transfer to H10W 72/01335>
D	H01L 2224/27466	<administrative transfer to H10W 72/01331>
D	H01L 2224/2747	<administrative transfer to H10W 72/013>
D	H01L 2224/27472	<administrative transfer to H10W 72/013>
D	H01L 2224/27474	<administrative transfer to H10W 72/013>
D	H01L 2224/2748	<administrative transfer to H10W 72/013>
D	H01L 2224/275	<administrative transfer to H10W 72/01361>
D	H01L 2224/27502	<administrative transfer to H10W 72/01361>
D	H01L 2224/27505	<administrative transfer to H10W 72/01361>
D	H01L 2224/2751	<administrative transfer to H10W 72/01361>
D	H01L 2224/27515	<administrative transfer to H10W 72/01361>
D	H01L 2224/2752	<administrative transfer to H10W 72/01361>
D	H01L 2224/27522	<administrative transfer to H10W 72/01361>
D	H01L 2224/27524	<administrative transfer to H10W 72/01361>
D	H01L 2224/27526	<administrative transfer to H10W 72/01361>
D	H01L 2224/2755	<administrative transfer to H10W 72/01361>
D	H01L 2224/27552	<administrative transfer to H10W 72/01361>
D	H01L 2224/27554	<administrative transfer to H10W 72/01361>
D	H01L 2224/276	<administrative transfer to H10W 72/01351>
D	H01L 2224/27602	<administrative transfer to H10W 72/01351>
D	H01L 2224/2761	<administrative transfer to H10W 72/01353>
D	H01L 2224/27612	<administrative transfer to H10W 72/01353>
D	H01L 2224/27614	<administrative transfer to H10W 72/01353>
D	H01L 2224/27616	<administrative transfer to H10W 72/01353>
D	H01L 2224/27618	<administrative transfer to H10W 72/01351>
D	H01L 2224/2762	<administrative transfer to H10W 72/01355>
D	H01L 2224/27622	<administrative transfer to H10W 72/01355>
D	H01L 2224/2763	<administrative transfer to H10W 72/01351>
D	H01L 2224/27632	<administrative transfer to H10W 72/01351>
D	H01L 2224/277	<administrative transfer to H10W 72/013>
D	H01L 2224/278	<administrative transfer to H10W 72/013>
D	H01L 2224/2781	<administrative transfer to H10W 72/01371>
D	H01L 2224/2782	<administrative transfer to H10W 72/01315>
D	H01L 2224/27821	<administrative transfer to H10W 72/01315>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/27822	<administrative transfer to H10W 72/01315>
D	H01L 2224/27823	<administrative transfer to H10W 72/01315>
D	H01L 2224/27824	<administrative transfer to H10W 72/01315>
D	H01L 2224/27825	<administrative transfer to H10W 72/01315>
D	H01L 2224/27826	<administrative transfer to H10W 72/01315>
D	H01L 2224/27827	<administrative transfer to H10W 72/01315>
D	H01L 2224/2783	<administrative transfer to H10W 72/01351>
D	H01L 2224/27831	<administrative transfer to H10W 72/01353>
D	H01L 2224/2784	<administrative transfer to H10W 72/01351>
D	H01L 2224/27845	<administrative transfer to H10W 72/01359>
D	H01L 2224/27848	<administrative transfer to H10W 72/01365>
D	H01L 2224/27849	<administrative transfer to H10W 72/01357>
D	H01L 2224/279	<administrative transfer to H10W 72/013>
D	H01L 2224/27901	<administrative transfer to H10W 72/013>
D	H01L 2224/27902	<administrative transfer to H10W 72/013>
D	H01L 2224/27903	<administrative transfer to H10W 72/013>
D	H01L 2224/27906	<administrative transfer to H10W 72/013>
D	H01L 2224/2791	<administrative transfer to H10W 72/013>
D	H01L 2224/27912	<administrative transfer to H10W 72/013>
D	H01L 2224/27916	<administrative transfer to H10W 72/013>
D	H01L 2224/28	<administrative transfer to H10W 72/30>
D	H01L 2224/28105	<administrative transfer to H10W 72/341>
D	H01L 2224/29	<administrative transfer to H10W 72/30>
D	H01L 2224/29001	<administrative transfer to H10W 72/30>
D	H01L 2224/29005	<administrative transfer to H10W 72/321>
D	H01L 2224/29006	<administrative transfer to H10W 72/321>
D	H01L 2224/29007	<administrative transfer to H10W 72/321>
D	H01L 2224/29008	<administrative transfer to H10W 72/321>
D	H01L 2224/29009	<administrative transfer to H10W 72/321>
D	H01L 2224/2901	<administrative transfer to H10W 72/331>
D	H01L 2224/29011	<administrative transfer to H10W 72/331>
D	H01L 2224/29012	<administrative transfer to H10W 72/332>
D	H01L 2224/29013	<administrative transfer to H10W 72/332>
D	H01L 2224/29014	<administrative transfer to H10W 72/332>
D	H01L 2224/29015	<administrative transfer to H10W 72/332>
D	H01L 2224/29016	<administrative transfer to H10W 72/334>
D	H01L 2224/29017	<administrative transfer to H10W 72/334>
D	H01L 2224/29018	<administrative transfer to H10W 72/334>
D	H01L 2224/29019	<administrative transfer to H10W 72/334>
D	H01L 2224/2902	<administrative transfer to H10W 72/341>
D	H01L 2224/29021	<administrative transfer to H10W 72/342>
D	H01L 2224/29022	<administrative transfer to H10W 72/342>
D	H01L 2224/29023	<administrative transfer to H10W 72/342>
D	H01L 2224/29024	<administrative transfer to H10W 72/344>
D	H01L 2224/29025	<administrative transfer to H10W 72/344>
D	H01L 2224/29026	<administrative transfer to H10W 72/344>
D	H01L 2224/29027	<administrative transfer to H10W 72/344>
D	H01L 2224/29028	<administrative transfer to H10W 72/344>
D	H01L 2224/29034	<administrative transfer to H10W 72/344>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/29035	<administrative transfer to H10W 72/344>
D	H01L 2224/29036	<administrative transfer to H10W 72/344>
D	H01L 2224/29075	<administrative transfer to H10W 72/321>
D	H01L 2224/29076	<administrative transfer to H10W 72/321>
D	H01L 2224/29078	<administrative transfer to H10W 72/324>
D	H01L 2224/2908	<administrative transfer to H10W 72/322>
D	H01L 2224/29082	<administrative transfer to H10W 72/322>
D	H01L 2224/29083	<administrative transfer to H10W 72/322>
D	H01L 2224/29084	<administrative transfer to H10W 72/322>
D	H01L 2224/29099	<administrative transfer to H10W 72/351>
D	H01L 2224/291	<administrative transfer to H10W 72/352>
D	H01L 2224/29101	<administrative transfer to H10W 72/352>
D	H01L 2224/29105	<administrative transfer to H10W 72/352>
D	H01L 2224/29109	<administrative transfer to H10W 72/352>
D	H01L 2224/29111	<administrative transfer to H10W 72/352>
D	H01L 2224/29113	<administrative transfer to H10W 72/352>
D	H01L 2224/29114	<administrative transfer to H10W 72/352>
D	H01L 2224/29116	<administrative transfer to H10W 72/352>
D	H01L 2224/29117	<administrative transfer to H10W 72/352>
D	H01L 2224/29118	<administrative transfer to H10W 72/352>
D	H01L 2224/2912	<administrative transfer to H10W 72/352>
D	H01L 2224/29123	<administrative transfer to H10W 72/352>
D	H01L 2224/29124	<administrative transfer to H10W 72/352>
D	H01L 2224/29138	<administrative transfer to H10W 72/352>
D	H01L 2224/29139	<administrative transfer to H10W 72/352>
D	H01L 2224/29144	<administrative transfer to H10W 72/352>
D	H01L 2224/29147	<administrative transfer to H10W 72/352>
D	H01L 2224/29149	<administrative transfer to H10W 72/352>
D	H01L 2224/29155	<administrative transfer to H10W 72/352>
D	H01L 2224/29157	<administrative transfer to H10W 72/352>
D	H01L 2224/2916	<administrative transfer to H10W 72/352>
D	H01L 2224/29163	<administrative transfer to H10W 72/352>
D	H01L 2224/29164	<administrative transfer to H10W 72/352>
D	H01L 2224/29166	<administrative transfer to H10W 72/352>
D	H01L 2224/29169	<administrative transfer to H10W 72/352>
D	H01L 2224/2917	<administrative transfer to H10W 72/352>
D	H01L 2224/29171	<administrative transfer to H10W 72/352>
D	H01L 2224/29172	<administrative transfer to H10W 72/352>
D	H01L 2224/29173	<administrative transfer to H10W 72/352>
D	H01L 2224/29176	<administrative transfer to H10W 72/352>
D	H01L 2224/29178	<administrative transfer to H10W 72/352>
D	H01L 2224/29179	<administrative transfer to H10W 72/352>
D	H01L 2224/2918	<administrative transfer to H10W 72/352>
D	H01L 2224/29181	<administrative transfer to H10W 72/352>
D	H01L 2224/29183	<administrative transfer to H10W 72/352>
D	H01L 2224/29184	<administrative transfer to H10W 72/352>
D	H01L 2224/29186	<administrative transfer to H10W 72/353>
D	H01L 2224/29187	<administrative transfer to H10W 72/353>
D	H01L 2224/29188	<administrative transfer to H10W 72/353>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/2919	<administrative transfer to H10W 72/354>
D	H01L 2224/29191	<administrative transfer to H10W 72/354>
D	H01L 2224/29193	<administrative transfer to H10W 72/353>
D	H01L 2224/29194	<administrative transfer to H10W 72/353>
D	H01L 2224/29195	<administrative transfer to H10W 72/353>
D	H01L 2224/29198	<administrative transfer to H10W 72/325 and H10W 72/351 simultaneously>
D	H01L 2224/29199	<administrative transfer to H10W 72/325 and H10W 72/351 simultaneously>
D	H01L 2224/292	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29201	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29205	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29209	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29211	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29213	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29214	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29216	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29217	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29218	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/2922	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29223	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29224	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29238	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29239	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29244	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29247	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29249	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29255	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29257	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/2926	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29263	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29264	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29266	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29269	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/2927	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29271	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29272	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29273	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29276	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29278	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29279	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/2928	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29281	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29283	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29284	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29286	<administrative transfer to H10W 72/325 and H10W 72/353 simultaneously>
D	H01L 2224/29287	<administrative transfer to H10W 72/325 and H10W 72/353 simultaneously>
D	H01L 2224/29288	<administrative transfer to H10W 72/325 and H10W 72/353 simultaneously>
D	H01L 2224/2929	<administrative transfer to H10W 72/325 and H10W 72/354 simultaneously>
D	H01L 2224/29291	<administrative transfer to H10W 72/325 and H10W 72/354 simultaneously>
D	H01L 2224/29293	<administrative transfer to H10W 72/325 and H10W 72/353 simultaneously>
D	H01L 2224/29294	<administrative transfer to H10W 72/325 and H10W 72/353 simultaneously>
D	H01L 2224/29295	<administrative transfer to H10W 72/325 and H10W 72/353 simultaneously>
D	H01L 2224/29298	<administrative transfer to H10W 72/325 and H10W 72/351 simultaneously>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/29299	<administrative transfer to H10W 72/325 and H10W 72/351 simultaneously>
D	H01L 2224/293	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29301	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29305	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29309	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29311	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29313	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29314	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29316	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29317	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29318	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/2932	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29323	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29324	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29338	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29339	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29344	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29347	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29349	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29355	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29357	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/2936	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29363	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29364	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29366	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/29369	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/2937	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29371	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29372	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29373	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29376	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29378	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29379	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/2938	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29381	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29383	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29384	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29386	<administrative transfer to H10W 72/325 and H10W 72/353 simultaneously>
D	H01L 2224/29387	<administrative transfer to H10W 72/325 and H10W 72/353 simultaneously>
D	H01L 2224/29388	<administrative transfer to H10W 72/325 and H10W 72/353 simultaneously>
D	H01L 2224/2939	<administrative transfer to H10W 72/325 and H10W 72/354 simultaneously>
D	H01L 2224/29391	<administrative transfer to H10W 72/325 and H10W 72/354 simultaneously>
D	H01L 2224/29393	<administrative transfer to H10W 72/325 and H10W 72/353 simultaneously>
D	H01L 2224/29394	<administrative transfer to H10W 72/325 and H10W 72/353 simultaneously>
D	H01L 2224/29395	<administrative transfer to H10W 72/325 and H10W 72/353 simultaneously>
D	H01L 2224/29398	<administrative transfer to H10W 72/325 and H10W 72/351 simultaneously>
D	H01L 2224/29399	<administrative transfer to H10W 72/325 and H10W 72/351 simultaneously>
D	H01L 2224/294	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29401	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29405	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/29409	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29411	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29413	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29414	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29416	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29417	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29418	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/2942	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29423	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29424	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29438	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29439	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29444	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29447	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29449	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29455	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29457	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/2946	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29463	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29464	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29466	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29469	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/2947	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29471	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29472	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/29473	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29476	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29478	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29479	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/2948	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29481	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29483	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29484	<administrative transfer to H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29486	<administrative transfer to H10W 72/325 and H10W 72/353 simultaneously>
D	H01L 2224/29487	<administrative transfer to H10W 72/325 and H10W 72/353 simultaneously>
D	H01L 2224/29488	<administrative transfer to H10W 72/325 and H10W 72/353 simultaneously>
D	H01L 2224/2949	<administrative transfer to H10W 72/325 and H10W 72/354 simultaneously>
D	H01L 2224/29491	<administrative transfer to H10W 72/325 and H10W 72/354 simultaneously>
D	H01L 2224/29493	<administrative transfer to H10W 72/325 and H10W 72/353 simultaneously>
D	H01L 2224/29494	<administrative transfer to H10W 72/325 and H10W 72/353 simultaneously>
D	H01L 2224/29495	<administrative transfer to H10W 72/325 and H10W 72/353 simultaneously>
D	H01L 2224/29498	<administrative transfer to H10W 72/325 and H10W 72/351 simultaneously>
D	H01L 2224/29499	<administrative transfer to H10W 72/325 and H10W 72/351 simultaneously>
D	H01L 2224/2954	<administrative transfer to H10W 72/322>
D	H01L 2224/29541	<administrative transfer to H10W 72/323>
D	H01L 2224/2955	<administrative transfer to H10W 72/335>
D	H01L 2224/29551	<administrative transfer to H10W 72/335>
D	H01L 2224/29552	<administrative transfer to H10W 72/335>
D	H01L 2224/29553	<administrative transfer to H10W 72/335>
D	H01L 2224/2956	<administrative transfer to H10W 72/345>
D	H01L 2224/29561	<administrative transfer to H10W 72/345>
D	H01L 2224/29562	<administrative transfer to H10W 72/345>
D	H01L 2224/29563	<administrative transfer to H10W 72/345>
D	H01L 2224/29564	<administrative transfer to H10W 72/345>
D	H01L 2224/29565	<administrative transfer to H10W 72/345>
D	H01L 2224/29566	<administrative transfer to H10W 72/345>
D	H01L 2224/2957	<administrative transfer to H10W 72/322>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/29575	<administrative transfer to H10W 72/323>
D	H01L 2224/29576	<administrative transfer to H10W 72/323>
D	H01L 2224/29578	<administrative transfer to H10W 72/323>
D	H01L 2224/2958	<administrative transfer to H10W 72/323>
D	H01L 2224/29582	<administrative transfer to H10W 72/323>
D	H01L 2224/29583	<administrative transfer to H10W 72/323>
D	H01L 2224/29584	<administrative transfer to H10W 72/323>
D	H01L 2224/29599	<administrative transfer to H10W 72/355 and H10W 72/351 simultaneously>
D	H01L 2224/296	<administrative transfer to H10W 72/355 and H10W 72/352 simultaneously>
D	H01L 2224/29601	<administrative transfer to H10W 72/355 and H10W 72/352 simultaneously>
D	H01L 2224/29605	<administrative transfer to H10W 72/355 and H10W 72/352 simultaneously>
D	H01L 2224/29609	<administrative transfer to H10W 72/355 and H10W 72/352 simultaneously>
D	H01L 2224/29611	<administrative transfer to H10W 72/355 and H10W 72/352 simultaneously>
D	H01L 2224/29613	<administrative transfer to H10W 72/355 and H10W 72/352 simultaneously>
D	H01L 2224/29614	<administrative transfer to H10W 72/355 and H10W 72/352 simultaneously>
D	H01L 2224/29616	<administrative transfer to H10W 72/355 and H10W 72/352 simultaneously>
D	H01L 2224/29617	<administrative transfer to H10W 72/355 and H10W 72/352 simultaneously>
D	H01L 2224/29618	<administrative transfer to H10W 72/355 and H10W 72/352 simultaneously>
D	H01L 2224/2962	<administrative transfer to H10W 72/355 and H10W 72/352 simultaneously>
D	H01L 2224/29623	<administrative transfer to H10W 72/355 and H10W 72/352 simultaneously>
D	H01L 2224/29624	<administrative transfer to H10W 72/355 and H10W 72/352 simultaneously>
D	H01L 2224/29638	<administrative transfer to H10W 72/355 and H10W 72/352 simultaneously>
D	H01L 2224/29639	<administrative transfer to H10W 72/355 and H10W 72/352 simultaneously>
D	H01L 2224/29644	<administrative transfer to H10W 72/355 and H10W 72/352 simultaneously>
D	H01L 2224/29647	<administrative transfer to H10W 72/355 and H10W 72/352 simultaneously>
D	H01L 2224/29649	<administrative transfer to H10W 72/355 and H10W 72/352 simultaneously>
D	H01L 2224/29655	<administrative transfer to H10W 72/355 and H10W 72/352 simultaneously>
D	H01L 2224/29657	<administrative transfer to H10W 72/355 and H10W 72/352 simultaneously>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/2966	<administrative transfer to H10W 72/355 and H10W 72/352 simultaneously>
D	H01L 2224/29663	<administrative transfer to H10W 72/355 and H10W 72/352 simultaneously>
D	H01L 2224/29664	<administrative transfer to H10W 72/355 and H10W 72/352 simultaneously>
D	H01L 2224/29666	<administrative transfer to H10W 72/355 and H10W 72/352 simultaneously>
D	H01L 2224/29669	<administrative transfer to H10W 72/355 and H10W 72/352 simultaneously>
D	H01L 2224/2967	<administrative transfer to H10W 72/355 and H10W 72/352 simultaneously>
D	H01L 2224/29671	<administrative transfer to H10W 72/355 and H10W 72/352 simultaneously>
D	H01L 2224/29672	<administrative transfer to H10W 72/355 and H10W 72/352 simultaneously>
D	H01L 2224/29673	<administrative transfer to H10W 72/355 and H10W 72/352 simultaneously>
D	H01L 2224/29676	<administrative transfer to H10W 72/355 and H10W 72/352 simultaneously>
D	H01L 2224/29678	<administrative transfer to H10W 72/355 and H10W 72/352 simultaneously>
D	H01L 2224/29679	<administrative transfer to H10W 72/355 and H10W 72/352 simultaneously>
D	H01L 2224/2968	<administrative transfer to H10W 72/355 and H10W 72/352 simultaneously>
D	H01L 2224/29681	<administrative transfer to H10W 72/355 and H10W 72/352 simultaneously>
D	H01L 2224/29683	<administrative transfer to H10W 72/355 and H10W 72/352 simultaneously>
D	H01L 2224/29684	<administrative transfer to H10W 72/355 and H10W 72/352 simultaneously>
D	H01L 2224/29686	<administrative transfer to H10W 72/355 and H10W 72/353 simultaneously>
D	H01L 2224/29687	<administrative transfer to H10W 72/355 and H10W 72/353 simultaneously>
D	H01L 2224/29688	<administrative transfer to H10W 72/355 and H10W 72/353 simultaneously>
D	H01L 2224/2969	<administrative transfer to H10W 72/355 and H10W 72/354 simultaneously>
D	H01L 2224/29691	<administrative transfer to H10W 72/355 and H10W 72/354 simultaneously>
D	H01L 2224/29693	<administrative transfer to H10W 72/355 and H10W 72/353 simultaneously>
D	H01L 2224/29694	<administrative transfer to H10W 72/355 and H10W 72/353 simultaneously>
D	H01L 2224/29695	<administrative transfer to H10W 72/355 and H10W 72/353 simultaneously>
D	H01L 2224/29698	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/351 simultaneously>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/29699	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/351 simultaneously>
D	H01L 2224/297	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29701	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29705	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29709	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29711	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29713	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29714	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29716	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29717	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29718	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/2972	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29723	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29724	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29738	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29739	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29744	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29747	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29749	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29755	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29757	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/2976	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29763	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29764	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29766	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/29769	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/2977	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29771	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29772	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29773	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29776	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29778	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29779	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/2978	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29781	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29783	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29784	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29786	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/353 simultaneously>
D	H01L 2224/29787	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/353 simultaneously>
D	H01L 2224/29788	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/353 simultaneously>
D	H01L 2224/2979	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/354 simultaneously>
D	H01L 2224/29791	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/354 simultaneously>
D	H01L 2224/29793	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/353 simultaneously>
D	H01L 2224/29794	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/353 simultaneously>
D	H01L 2224/29795	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/353 simultaneously>
D	H01L 2224/29798	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/351 simultaneously>
D	H01L 2224/29799	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/351 simultaneously>
D	H01L 2224/298	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29801	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29805	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/29809	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29811	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29813	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29814	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29816	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29817	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29818	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/2982	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29823	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29824	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29838	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29839	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29844	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29847	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29849	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29855	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29857	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/2986	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29863	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29864	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29866	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29869	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/2987	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29871	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29872	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/29873	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29876	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29878	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29879	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/2988	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29881	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29883	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29884	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29886	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/353 simultaneously>
D	H01L 2224/29887	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/353 simultaneously>
D	H01L 2224/29888	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/353 simultaneously>
D	H01L 2224/2989	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/354 simultaneously>
D	H01L 2224/29891	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/354 simultaneously>
D	H01L 2224/29893	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/353 simultaneously>
D	H01L 2224/29894	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/353 simultaneously>
D	H01L 2224/29895	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/353 simultaneously>
D	H01L 2224/29898	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/351 simultaneously>
D	H01L 2224/29899	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/351 simultaneously>
D	H01L 2224/299	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29901	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29905	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29909	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29911	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29913	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29914	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/29916	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29917	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29918	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/2992	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29923	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29924	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29938	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29939	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29944	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29947	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29949	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29955	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29957	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/2996	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29963	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29964	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29966	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29969	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/2997	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29971	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29972	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29973	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29976	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29978	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29979	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/2998	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29981	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29983	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29984	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/352 simultaneously>
D	H01L 2224/29986	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/353 simultaneously>
D	H01L 2224/29987	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/353 simultaneously>
D	H01L 2224/29988	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/353 simultaneously>
D	H01L 2224/2999	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/354 simultaneously>
D	H01L 2224/29991	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/354 simultaneously>
D	H01L 2224/29993	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/353 simultaneously>
D	H01L 2224/29994	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/353 simultaneously>
D	H01L 2224/29995	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/353 simultaneously>
D	H01L 2224/29998	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/351 simultaneously>
D	H01L 2224/29999	<administrative transfer to H10W 72/355, H10W 72/325 and H10W 72/351 simultaneously>
D	H01L 2224/30	<administrative transfer to H10W 72/30>
D	H01L 2224/3001	<administrative transfer to H10W 72/328>
D	H01L 2224/3003	<administrative transfer to H10W 72/327>
D	H01L 2224/3005	<administrative transfer to H10W 72/337>
D	H01L 2224/30051	<administrative transfer to H10W 72/337>
D	H01L 2224/301	<administrative transfer to H10W 72/347>
D	H01L 2224/30104	<administrative transfer to H10W 72/347 and H10W 72/344 simultaneously>
D	H01L 2224/3011	<administrative transfer to H10W 72/347 and H10W 72/344 simultaneously>
D	H01L 2224/3012	<administrative transfer to H10W 72/348>
D	H01L 2224/3013	<administrative transfer to H10W 72/348>
D	H01L 2224/30131	<administrative transfer to H10W 72/348>
D	H01L 2224/30132	<administrative transfer to H10W 72/348>
D	H01L 2224/30133	<administrative transfer to H10W 72/348>
D	H01L 2224/30134	<administrative transfer to H10W 72/348>
D	H01L 2224/30135	<administrative transfer to H10W 72/348>
D	H01L 2224/30136	<administrative transfer to H10W 72/348>
D	H01L 2224/3014	<administrative transfer to H10W 72/348>
D	H01L 2224/30141	<administrative transfer to H10W 72/348>
D	H01L 2224/30142	<administrative transfer to H10W 72/348>
D	H01L 2224/30143	<administrative transfer to H10W 72/348>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/30145	<administrative transfer to H10W 72/348>
D	H01L 2224/30146	<administrative transfer to H10W 72/348>
D	H01L 2224/3015	<administrative transfer to H10W 72/348>
D	H01L 2224/30151	<administrative transfer to H10W 72/348>
D	H01L 2224/30152	<administrative transfer to H10W 72/348>
D	H01L 2224/30153	<administrative transfer to H10W 72/348>
D	H01L 2224/30154	<administrative transfer to H10W 72/348>
D	H01L 2224/30155	<administrative transfer to H10W 72/348>
D	H01L 2224/30156	<administrative transfer to H10W 72/348>
D	H01L 2224/3016	<administrative transfer to H10W 72/348>
D	H01L 2224/30163	<administrative transfer to H10W 72/348>
D	H01L 2224/30164	<administrative transfer to H10W 72/348>
D	H01L 2224/30165	<administrative transfer to H10W 72/348>
D	H01L 2224/30166	<administrative transfer to H10W 72/348>
D	H01L 2224/30177	<administrative transfer to H10W 72/348>
D	H01L 2224/30179	<administrative transfer to H10W 72/348>
D	H01L 2224/3018	<administrative transfer to H10W 72/347>
D	H01L 2224/30181	<administrative transfer to H10W 72/347>
D	H01L 2224/30183	<administrative transfer to H10W 72/347>
D	H01L 2224/305	<administrative transfer to H10W 72/357>
D	H01L 2224/30505	<administrative transfer to H10W 72/357>
D	H01L 2224/3051	<administrative transfer to H10W 72/367>
D	H01L 2224/30515	<administrative transfer to H10W 72/367>
D	H01L 2224/30517	<administrative transfer to H10W 72/367>
D	H01L 2224/30519	<administrative transfer to H10W 72/367 and H10W 72/365 simultaneously>
D	H01L 2224/31	<administrative transfer to H10W 72/07351 and H10W 72/30 simultaneously>
D	H01L 2224/32	<administrative transfer to H10W 72/07351 and H10W 72/30 simultaneously>
D	H01L 2224/3201	<administrative transfer to H10W 72/07352 and H10W 72/321 simultaneously>
D	H01L 2224/32012	<administrative transfer to H10W 72/07352 and H10W 72/321 simultaneously>
D	H01L 2224/32013	<administrative transfer to H10W 72/07352 and H10W 72/321 simultaneously>
D	H01L 2224/32014	<administrative transfer to H10W 72/07352 and H10W 72/321 simultaneously>
D	H01L 2224/3205	<administrative transfer to H10W 72/07353 and H10W 72/331 simultaneously>
D	H01L 2224/32052	<administrative transfer to H10W 72/07353 and H10W 72/332 simultaneously>
D	H01L 2224/32053	<administrative transfer to H10W 72/07353 and H10W 72/332 simultaneously>
D	H01L 2224/32054	<administrative transfer to H10W 72/07353 and H10W 72/332 simultaneously>
D	H01L 2224/32055	<administrative transfer to H10W 72/07353 and H10W 72/332 simultaneously>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/32056	<administrative transfer to H10W 72/07353 and H10W 72/332 simultaneously>
D	H01L 2224/32057	<administrative transfer to H10W 72/07353 and H10W 72/334 simultaneously>
D	H01L 2224/32058	<administrative transfer to H10W 72/07353 and H10W 72/334 simultaneously>
D	H01L 2224/32059	<administrative transfer to H10W 72/07353 and H10W 72/334 simultaneously>
D	H01L 2224/3207	<administrative transfer to H10W 72/07353 and H10W 72/331 simultaneously>
D	H01L 2224/321	<administrative transfer to H10W 72/07354 and H10W 72/341 simultaneously>
D	H01L 2224/32104	<administrative transfer to H10W 72/07354 and H10W 72/344 simultaneously>
D	H01L 2224/32105	<administrative transfer to H10W 72/07354 and H10W 72/344 simultaneously>
D	H01L 2224/32106	<administrative transfer to H10W 72/07354 and H10W 72/344 simultaneously>
D	H01L 2224/32111	<administrative transfer to H10W 72/07354 and H10W 72/342 simultaneously>
D	H01L 2224/32112	<administrative transfer to H10W 72/07354 and H10W 72/342 simultaneously>
D	H01L 2224/32113	<administrative transfer to H10W 72/07354 and H10W 72/342 simultaneously>
D	H01L 2224/3213	<administrative transfer to H10W 72/07354 and H10W 72/341 simultaneously>
D	H01L 2224/32135	<administrative transfer to H10W 90/731>
D	H01L 2224/32137	<administrative transfer to H10W 90/733>
D	H01L 2224/32141	<administrative transfer to H10W 90/731>
D	H01L 2224/32145	<administrative transfer to H10W 90/732>
D	H01L 2224/32146	<administrative transfer to H10W 90/732>
D	H01L 2224/32147	<administrative transfer to H10W 90/732>
D	H01L 2224/32148	<administrative transfer to H10W 90/732>
D	H01L 2224/32151	<administrative transfer to H10W 90/731>
D	H01L 2224/32153	<administrative transfer to H10W 90/731>
D	H01L 2224/32155	<administrative transfer to H10W 90/735>
D	H01L 2224/32157	<administrative transfer to H10W 90/735>
D	H01L 2224/3216	<administrative transfer to H10W 90/735>
D	H01L 2224/32163	<administrative transfer to H10W 90/735>
D	H01L 2224/32165	<administrative transfer to H10W 90/735>
D	H01L 2224/32167	<administrative transfer to H10W 90/735>
D	H01L 2224/32168	<administrative transfer to H10W 90/735>
D	H01L 2224/32175	<administrative transfer to H10W 90/737>
D	H01L 2224/32183	<administrative transfer to H10W 90/737>
D	H01L 2224/32187	<administrative transfer to H10W 90/737>
D	H01L 2224/32188	<administrative transfer to H10W 90/737>
D	H01L 2224/32195	<administrative transfer to H10W 90/739>
D	H01L 2224/32197	<administrative transfer to H10W 90/739>
D	H01L 2224/32198	<administrative transfer to H10W 90/739>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/32221	<administrative transfer to H10W 90/731>
D	H01L 2224/32225	<administrative transfer to H10W 90/734>
D	H01L 2224/32227	<administrative transfer to H10W 90/734>
D	H01L 2224/3223	<administrative transfer to H10W 90/734>
D	H01L 2224/32233	<administrative transfer to H10W 90/734>
D	H01L 2224/32235	<administrative transfer to H10W 90/734>
D	H01L 2224/32237	<administrative transfer to H10W 90/734>
D	H01L 2224/32238	<administrative transfer to H10W 90/734>
D	H01L 2224/3224	<administrative transfer to H10W 90/734>
D	H01L 2224/32245	<administrative transfer to H10W 90/736>
D	H01L 2224/32253	<administrative transfer to H10W 90/736>
D	H01L 2224/32257	<administrative transfer to H10W 90/736>
D	H01L 2224/32258	<administrative transfer to H10W 90/736>
D	H01L 2224/3226	<administrative transfer to H10W 90/736>
D	H01L 2224/32265	<administrative transfer to H10W 90/738>
D	H01L 2224/32267	<administrative transfer to H10W 90/738>
D	H01L 2224/32268	<administrative transfer to H10W 90/738>
D	H01L 2224/325	<administrative transfer to H10W 72/07355 and H10W 72/351 simultaneously>
D	H01L 2224/32501	<administrative transfer to H10W 72/07355 and H10W 72/351 simultaneously>
D	H01L 2224/32502	<administrative transfer to H10W 72/07355 and H10W 72/3524 simultaneously>
D	H01L 2224/32503	<administrative transfer to H10W 72/07355 and H10W 72/3528 simultaneously>
D	H01L 2224/32505	<administrative transfer to H10W 72/07355 and H10W 72/351 simultaneously>
D	H01L 2224/32506	<administrative transfer to H10W 72/07355 and H10W 72/3524 simultaneously>
D	H01L 2224/32507	<administrative transfer to H10W 72/07355 and H10W 72/3528 simultaneously>
D	H01L 2224/33	<administrative transfer to H10W 72/07351 and H10W 72/30 simultaneously>
D	H01L 2224/3301	<administrative transfer to H10W 72/07352 and H10W 72/328 simultaneously>
D	H01L 2224/3303	<administrative transfer to H10W 72/07352 and H10W 72/327 simultaneously>
D	H01L 2224/3305	<administrative transfer to H10W 72/07353 and H10W 72/337 simultaneously>
D	H01L 2224/33051	<administrative transfer to H10W 72/07353 and H10W 72/337 simultaneously>
D	H01L 2224/33055	<administrative transfer to H10W 72/07353 and H10W 72/337 simultaneously>
D	H01L 2224/331	<administrative transfer to H10W 72/07354 and H10W 72/347 simultaneously>
D	H01L 2224/33104	<administrative transfer to H10W 72/07354, H10W 72/344 and H10W 72/347 simultaneously>
D	H01L 2224/33106	<administrative transfer to H10W 72/07354, H10W 72/344 and H10W 72/347 simultaneously>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/33107	<administrative transfer to H10W 72/07354, H10W 72/344 and H10W 72/347 simultaneously>
D	H01L 2224/3312	<administrative transfer to H10W 72/07354 and H10W 72/348 simultaneously>
D	H01L 2224/3313	<administrative transfer to H10W 72/07354 and H10W 72/348 simultaneously>
D	H01L 2224/33132	<administrative transfer to H10W 72/07354 and H10W 72/348 simultaneously>
D	H01L 2224/33133	<administrative transfer to H10W 72/07354 and H10W 72/348 simultaneously>
D	H01L 2224/33134	<administrative transfer to H10W 72/07354 and H10W 72/348 simultaneously>
D	H01L 2224/33135	<administrative transfer to H10W 72/07354 and H10W 72/348 simultaneously>
D	H01L 2224/3314	<administrative transfer to H10W 72/07354 and H10W 72/348 simultaneously>
D	H01L 2224/33142	<administrative transfer to H10W 72/07354 and H10W 72/348 simultaneously>
D	H01L 2224/33143	<administrative transfer to H10W 72/07354 and H10W 72/348 simultaneously>
D	H01L 2224/33144	<administrative transfer to H10W 72/07354 and H10W 72/348 simultaneously>
D	H01L 2224/33145	<administrative transfer to H10W 72/07354 and H10W 72/348 simultaneously>
D	H01L 2224/3315	<administrative transfer to H10W 72/07354 and H10W 72/348 simultaneously>
D	H01L 2224/33151	<administrative transfer to H10W 72/07354 and H10W 72/348 simultaneously>
D	H01L 2224/33152	<administrative transfer to H10W 72/07354 and H10W 72/348 simultaneously>
D	H01L 2224/33153	<administrative transfer to H10W 72/07354 and H10W 72/348 simultaneously>
D	H01L 2224/33154	<administrative transfer to H10W 72/07354 and H10W 72/348 simultaneously>
D	H01L 2224/33155	<administrative transfer to H10W 72/07354 and H10W 72/348 simultaneously>
D	H01L 2224/33156	<administrative transfer to H10W 72/07354 and H10W 72/348 simultaneously>
D	H01L 2224/3316	<administrative transfer to H10W 72/07354 and H10W 72/348 simultaneously>
D	H01L 2224/33163	<administrative transfer to H10W 72/07354 and H10W 72/348 simultaneously>
D	H01L 2224/33164	<administrative transfer to H10W 72/07354 and H10W 72/348 simultaneously>
D	H01L 2224/33165	<administrative transfer to H10W 72/07354 and H10W 72/348 simultaneously>
D	H01L 2224/33177	<administrative transfer to H10W 72/07354 and H10W 72/348 simultaneously>
D	H01L 2224/33179	<administrative transfer to H10W 72/07354 and H10W 72/348 simultaneously>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/3318	<administrative transfer to H10W 72/07354 and H10W 72/347 simultaneously>
D	H01L 2224/33181	<administrative transfer to H10W 72/07354 and H10W 72/347 simultaneously>
D	H01L 2224/33183	<administrative transfer to H10W 72/07354 and H10W 72/347 simultaneously>
D	H01L 2224/335	<administrative transfer to H10W 72/07355 and H10W 72/357 simultaneously>
D	H01L 2224/33505	<administrative transfer to H10W 72/07355 and H10W 72/357 simultaneously>
D	H01L 2224/3351	<administrative transfer to H10W 72/07351 and H10W 72/367 simultaneously>
D	H01L 2224/33515	<administrative transfer to H10W 72/07351 and H10W 72/367 simultaneously>
D	H01L 2224/33517	<administrative transfer to H10W 72/07351 and H10W 72/367 simultaneously>
D	H01L 2224/33519	<administrative transfer to H10W 72/07351, H10W 72/365 and H10W 72/367 simultaneously>
D	H01L 2224/34	<administrative transfer to H10W 72/016>
D	H01L 2224/35	<administrative transfer to H10W 72/016>
D	H01L 2224/35001	<administrative transfer to H10W 72/01604>
D	H01L 2224/351	<administrative transfer to H10W 72/016>
D	H01L 2224/3512	<administrative transfer to H10W 72/01615>
D	H01L 2224/35125	<administrative transfer to H10W 72/016>
D	H01L 2224/352	<administrative transfer to H10W 72/016>
D	H01L 2224/3521	<administrative transfer to H10W 72/016>
D	H01L 2224/355	<administrative transfer to H10W 72/016>
D	H01L 2224/3551	<administrative transfer to H10W 72/016>
D	H01L 2224/3552	<administrative transfer to H10W 72/016>
D	H01L 2224/357	<administrative transfer to H10W 72/016>
D	H01L 2224/358	<administrative transfer to H10W 72/016>
D	H01L 2224/3581	<administrative transfer to H10W 72/01671>
D	H01L 2224/3582	<administrative transfer to H10W 72/01615>
D	H01L 2224/35821	<administrative transfer to H10W 72/01615>
D	H01L 2224/35822	<administrative transfer to H10W 72/01615>
D	H01L 2224/35823	<administrative transfer to H10W 72/01615>
D	H01L 2224/35824	<administrative transfer to H10W 72/01615>
D	H01L 2224/35825	<administrative transfer to H10W 72/01615>
D	H01L 2224/35826	<administrative transfer to H10W 72/01615>
D	H01L 2224/35827	<administrative transfer to H10W 72/01615>
D	H01L 2224/3583	<administrative transfer to H10W 72/01651>
D	H01L 2224/35831	<administrative transfer to H10W 72/01661 and H10W 72/01653 simultaneously>
D	H01L 2224/35847	<administrative transfer to H10W 72/01661>
D	H01L 2224/35848	<administrative transfer to H10W 72/016>
D	H01L 2224/35985	<administrative transfer to H10W 72/016>
D	H01L 2224/35986	<administrative transfer to H10W 72/016>
D	H01L 2224/36	<administrative transfer to H10W 72/60>
D	H01L 2224/37	<administrative transfer to H10W 72/60>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/37001	<administrative transfer to H10W 72/60>
D	H01L 2224/37005	<administrative transfer to H10W 72/621>
D	H01L 2224/3701	<administrative transfer to H10W 72/631>
D	H01L 2224/37011	<administrative transfer to H10W 72/631>
D	H01L 2224/37012	<administrative transfer to H10W 72/634>
D	H01L 2224/37013	<administrative transfer to H10W 72/634>
D	H01L 2224/3702	<administrative transfer to H10W 72/641>
D	H01L 2224/37025	<administrative transfer to H10W 72/624>
D	H01L 2224/37026	<administrative transfer to H10W 72/624>
D	H01L 2224/37028	<administrative transfer to H10W 72/624>
D	H01L 2224/3703	<administrative transfer to H10W 72/623>
D	H01L 2224/37032	<administrative transfer to H10W 72/623>
D	H01L 2224/37033	<administrative transfer to H10W 72/623>
D	H01L 2224/37034	<administrative transfer to H10W 72/623>
D	H01L 2224/37099	<administrative transfer to H10W 72/651>
D	H01L 2224/371	<administrative transfer to H10W 72/652>
D	H01L 2224/37101	<administrative transfer to H10W 72/652>
D	H01L 2224/37105	<administrative transfer to H10W 72/652>
D	H01L 2224/37109	<administrative transfer to H10W 72/652>
D	H01L 2224/37111	<administrative transfer to H10W 72/652>
D	H01L 2224/37113	<administrative transfer to H10W 72/652>
D	H01L 2224/37114	<administrative transfer to H10W 72/652>
D	H01L 2224/37116	<administrative transfer to H10W 72/652>
D	H01L 2224/37117	<administrative transfer to H10W 72/652>
D	H01L 2224/37118	<administrative transfer to H10W 72/652>
D	H01L 2224/3712	<administrative transfer to H10W 72/652>
D	H01L 2224/37123	<administrative transfer to H10W 72/652>
D	H01L 2224/37124	<administrative transfer to H10W 72/652>
D	H01L 2224/37138	<administrative transfer to H10W 72/652>
D	H01L 2224/37139	<administrative transfer to H10W 72/652>
D	H01L 2224/37144	<administrative transfer to H10W 72/652>
D	H01L 2224/37147	<administrative transfer to H10W 72/652>
D	H01L 2224/37149	<administrative transfer to H10W 72/652>
D	H01L 2224/37155	<administrative transfer to H10W 72/652>
D	H01L 2224/37157	<administrative transfer to H10W 72/652>
D	H01L 2224/3716	<administrative transfer to H10W 72/652>
D	H01L 2224/37163	<administrative transfer to H10W 72/652>
D	H01L 2224/37164	<administrative transfer to H10W 72/652>
D	H01L 2224/37166	<administrative transfer to H10W 72/652>
D	H01L 2224/37169	<administrative transfer to H10W 72/652>
D	H01L 2224/3717	<administrative transfer to H10W 72/652>
D	H01L 2224/37171	<administrative transfer to H10W 72/652>
D	H01L 2224/37172	<administrative transfer to H10W 72/652>
D	H01L 2224/37173	<administrative transfer to H10W 72/652>
D	H01L 2224/37176	<administrative transfer to H10W 72/652>
D	H01L 2224/37178	<administrative transfer to H10W 72/652>
D	H01L 2224/37179	<administrative transfer to H10W 72/652>
D	H01L 2224/3718	<administrative transfer to H10W 72/652>
D	H01L 2224/37181	<administrative transfer to H10W 72/652>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/37183	<administrative transfer to H10W 72/652>
D	H01L 2224/37184	<administrative transfer to H10W 72/652>
D	H01L 2224/37186	<administrative transfer to H10W 72/653>
D	H01L 2224/37187	<administrative transfer to H10W 72/653>
D	H01L 2224/37188	<administrative transfer to H10W 72/653>
D	H01L 2224/3719	<administrative transfer to H10W 72/653>
D	H01L 2224/37191	<administrative transfer to H10W 72/653>
D	H01L 2224/37193	<administrative transfer to H10W 72/653>
D	H01L 2224/37194	<administrative transfer to H10W 72/653>
D	H01L 2224/37195	<administrative transfer to H10W 72/653>
D	H01L 2224/37198	<administrative transfer to H10W 72/625>
D	H01L 2224/37199	<administrative transfer to H10W 72/625>
D	H01L 2224/372	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37201	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37205	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37209	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37211	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37213	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37214	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37216	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37217	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37218	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/3722	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37223	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37224	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37238	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37239	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37244	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37247	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37249	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37255	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/37257	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/3726	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37263	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37264	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37266	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37269	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/3727	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37271	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37272	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37273	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37276	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37278	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37279	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/3728	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37281	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37283	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37284	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37286	<administrative transfer to H10W 72/625 and H10W 72/653 simultaneously>
D	H01L 2224/37287	<administrative transfer to H10W 72/625 and H10W 72/653 simultaneously>
D	H01L 2224/37288	<administrative transfer to H10W 72/625 and H10W 72/653 simultaneously>
D	H01L 2224/3729	<administrative transfer to H10W 72/625 and H10W 72/653 simultaneously>
D	H01L 2224/37291	<administrative transfer to H10W 72/625 and H10W 72/653 simultaneously>
D	H01L 2224/37293	<administrative transfer to H10W 72/625 and H10W 72/653 simultaneously>
D	H01L 2224/37294	<administrative transfer to H10W 72/625 and H10W 72/653 simultaneously>
D	H01L 2224/37295	<administrative transfer to H10W 72/625 and H10W 72/653 simultaneously>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/37298	<administrative transfer to H10W 72/625 and H10W 72/651 simultaneously>
D	H01L 2224/37299	<administrative transfer to H10W 72/625 and H10W 72/651 simultaneously>
D	H01L 2224/373	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37301	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37305	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37309	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37311	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37313	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37314	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37316	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37317	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37318	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/3732	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37323	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37324	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37338	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37339	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37344	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37347	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37349	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37355	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37357	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/3736	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37363	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37364	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/37366	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37369	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/3737	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37371	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37372	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37373	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37376	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37378	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37379	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/3738	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37381	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37383	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37384	<administrative transfer to H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37386	<administrative transfer to H10W 72/625 and H10W 72/653 simultaneously>
D	H01L 2224/37387	<administrative transfer to H10W 72/625 and H10W 72/653 simultaneously>
D	H01L 2224/37388	<administrative transfer to H10W 72/625 and H10W 72/653 simultaneously>
D	H01L 2224/3739	<administrative transfer to H10W 72/625 and H10W 72/653 simultaneously>
D	H01L 2224/37391	<administrative transfer to H10W 72/625 and H10W 72/653 simultaneously>
D	H01L 2224/37393	<administrative transfer to H10W 72/625 and H10W 72/653 simultaneously>
D	H01L 2224/37394	<administrative transfer to H10W 72/625 and H10W 72/653 simultaneously>
D	H01L 2224/37395	<administrative transfer to H10W 72/625 and H10W 72/653 simultaneously>
D	H01L 2224/37398	<administrative transfer to H10W 72/625 and H10W 72/653 simultaneously>
D	H01L 2224/37399	<administrative transfer to H10W 72/625, H10W 72/655 and H10W 72/651 simultaneously>
D	H01L 2224/374	<administrative transfer to H10W 72/625, H10W 72/655 and H10W 72/652 simultaneously>
D	H01L 2224/37401	<administrative transfer to H10W 72/625, H10W 72/655 and H10W 72/652 simultaneously>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/37405	<administrative transfer to H10W 72/625, H10W 72/655 and H10W 72/652 simultaneously>
D	H01L 2224/37409	<administrative transfer to H10W 72/625, H10W 72/655 and H10W 72/652 simultaneously>
D	H01L 2224/37411	<administrative transfer to H10W 72/625, H10W 72/655 and H10W 72/652 simultaneously>
D	H01L 2224/37413	<administrative transfer to H10W 72/625, H10W 72/655 and H10W 72/652 simultaneously>
D	H01L 2224/37414	<administrative transfer to H10W 72/625, H10W 72/655 and H10W 72/652 simultaneously>
D	H01L 2224/37416	<administrative transfer to H10W 72/625, H10W 72/655 and H10W 72/652 simultaneously>
D	H01L 2224/37417	<administrative transfer to H10W 72/625, H10W 72/655 and H10W 72/652 simultaneously>
D	H01L 2224/37418	<administrative transfer to H10W 72/625, H10W 72/655 and H10W 72/652 simultaneously>
D	H01L 2224/3742	<administrative transfer to H10W 72/625, H10W 72/655 and H10W 72/652 simultaneously>
D	H01L 2224/37423	<administrative transfer to H10W 72/625, H10W 72/655 and H10W 72/652 simultaneously>
D	H01L 2224/37424	<administrative transfer to H10W 72/625, H10W 72/655 and H10W 72/652 simultaneously>
D	H01L 2224/37438	<administrative transfer to H10W 72/625, H10W 72/655 and H10W 72/652 simultaneously>
D	H01L 2224/37439	<administrative transfer to H10W 72/625, H10W 72/655 and H10W 72/652 simultaneously>
D	H01L 2224/37444	<administrative transfer to H10W 72/625, H10W 72/655 and H10W 72/652 simultaneously>
D	H01L 2224/37447	<administrative transfer to H10W 72/625, H10W 72/655 and H10W 72/652 simultaneously>
D	H01L 2224/37449	<administrative transfer to H10W 72/625, H10W 72/655 and H10W 72/652 simultaneously>
D	H01L 2224/37455	<administrative transfer to H10W 72/625, H10W 72/655 and H10W 72/652 simultaneously>
D	H01L 2224/37457	<administrative transfer to H10W 72/625, H10W 72/655 and H10W 72/652 simultaneously>
D	H01L 2224/3746	<administrative transfer to H10W 72/625, H10W 72/655 and H10W 72/652 simultaneously>
D	H01L 2224/37463	<administrative transfer to H10W 72/625, H10W 72/655 and H10W 72/652 simultaneously>
D	H01L 2224/37464	<administrative transfer to H10W 72/625, H10W 72/655 and H10W 72/652 simultaneously>
D	H01L 2224/37466	<administrative transfer to H10W 72/625, H10W 72/655 and H10W 72/652 simultaneously>
D	H01L 2224/37469	<administrative transfer to H10W 72/625, H10W 72/655 and H10W 72/652 simultaneously>
D	H01L 2224/3747	<administrative transfer to H10W 72/625, H10W 72/655 and H10W 72/652 simultaneously>
D	H01L 2224/37471	<administrative transfer to H10W 72/625, H10W 72/655 and H10W 72/652 simultaneously>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/37472	<administrative transfer to H10W 72/625, H10W 72/655 and H10W 72/652 simultaneously>
D	H01L 2224/37473	<administrative transfer to H10W 72/625, H10W 72/655 and H10W 72/652 simultaneously>
D	H01L 2224/37476	<administrative transfer to H10W 72/625, H10W 72/655 and H10W 72/652 simultaneously>
D	H01L 2224/37478	<administrative transfer to H10W 72/625, H10W 72/655 and H10W 72/652 simultaneously>
D	H01L 2224/37479	<administrative transfer to H10W 72/625, H10W 72/655 and H10W 72/652 simultaneously>
D	H01L 2224/3748	<administrative transfer to H10W 72/625, H10W 72/655 and H10W 72/652 simultaneously>
D	H01L 2224/37481	<administrative transfer to H10W 72/625, H10W 72/655 and H10W 72/652 simultaneously>
D	H01L 2224/37483	<administrative transfer to H10W 72/625, H10W 72/655 and H10W 72/652 simultaneously>
D	H01L 2224/37484	<administrative transfer to H10W 72/625, H10W 72/655 and H10W 72/652 simultaneously>
D	H01L 2224/37486	<administrative transfer to H10W 72/625, H10W 72/655 and H10W 72/653 simultaneously>
D	H01L 2224/37487	<administrative transfer to H10W 72/625, H10W 72/655 and H10W 72/653 simultaneously>
D	H01L 2224/37488	<administrative transfer to H10W 72/625, H10W 72/655 and H10W 72/653 simultaneously>
D	H01L 2224/3749	<administrative transfer to H10W 72/625, H10W 72/655 and H10W 72/653 simultaneously>
D	H01L 2224/37491	<administrative transfer to H10W 72/625, H10W 72/655 and H10W 72/653 simultaneously>
D	H01L 2224/37493	<administrative transfer to H10W 72/625, H10W 72/655 and H10W 72/653 simultaneously>
D	H01L 2224/37494	<administrative transfer to H10W 72/625, H10W 72/655 and H10W 72/653 simultaneously>
D	H01L 2224/37495	<administrative transfer to H10W 72/625, H10W 72/655 and H10W 72/653 simultaneously>
D	H01L 2224/37498	<administrative transfer to H10W 72/625, H10W 72/655 and H10W 72/653 simultaneously>
D	H01L 2224/37499	<administrative transfer to H10W 72/625 and H10W 72/655 simultaneously>
D	H01L 2224/3754	<administrative transfer to H10W 72/622>
D	H01L 2224/37541	<administrative transfer to H10W 72/623>
D	H01L 2224/3755	<administrative transfer to H10W 72/635>
D	H01L 2224/3756	<administrative transfer to H10W 72/645>
D	H01L 2224/37565	<administrative transfer to H10W 72/622>
D	H01L 2224/3757	<administrative transfer to H10W 72/623>
D	H01L 2224/37572	<administrative transfer to H10W 72/623>
D	H01L 2224/37573	<administrative transfer to H10W 72/623>
D	H01L 2224/37574	<administrative transfer to H10W 72/623>
D	H01L 2224/37576	<administrative transfer to H10W 72/623>
D	H01L 2224/37578	<administrative transfer to H10W 72/623>
D	H01L 2224/37599	<administrative transfer to H10W 72/655>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/376	<administrative transfer to H10W 72/655 and H10W 72/652 simultaneously>
D	H01L 2224/37601	<administrative transfer to H10W 72/655 and H10W 72/652 simultaneously>
D	H01L 2224/37605	<administrative transfer to H10W 72/655 and H10W 72/652 simultaneously>
D	H01L 2224/37609	<administrative transfer to H10W 72/655 and H10W 72/652 simultaneously>
D	H01L 2224/37611	<administrative transfer to H10W 72/655 and H10W 72/652 simultaneously>
D	H01L 2224/37613	<administrative transfer to H10W 72/655 and H10W 72/652 simultaneously>
D	H01L 2224/37614	<administrative transfer to H10W 72/655 and H10W 72/652 simultaneously>
D	H01L 2224/37616	<administrative transfer to H10W 72/655 and H10W 72/652 simultaneously>
D	H01L 2224/37617	<administrative transfer to H10W 72/655 and H10W 72/652 simultaneously>
D	H01L 2224/37618	<administrative transfer to H10W 72/655 and H10W 72/652 simultaneously>
D	H01L 2224/3762	<administrative transfer to H10W 72/655 and H10W 72/652 simultaneously>
D	H01L 2224/37623	<administrative transfer to H10W 72/655 and H10W 72/652 simultaneously>
D	H01L 2224/37624	<administrative transfer to H10W 72/655 and H10W 72/652 simultaneously>
D	H01L 2224/37638	<administrative transfer to H10W 72/655 and H10W 72/652 simultaneously>
D	H01L 2224/37639	<administrative transfer to H10W 72/655 and H10W 72/652 simultaneously>
D	H01L 2224/37644	<administrative transfer to H10W 72/655 and H10W 72/652 simultaneously>
D	H01L 2224/37647	<administrative transfer to H10W 72/655 and H10W 72/652 simultaneously>
D	H01L 2224/37649	<administrative transfer to H10W 72/655 and H10W 72/652 simultaneously>
D	H01L 2224/37655	<administrative transfer to H10W 72/655 and H10W 72/652 simultaneously>
D	H01L 2224/37657	<administrative transfer to H10W 72/655 and H10W 72/652 simultaneously>
D	H01L 2224/3766	<administrative transfer to H10W 72/655 and H10W 72/652 simultaneously>
D	H01L 2224/37663	<administrative transfer to H10W 72/655 and H10W 72/652 simultaneously>
D	H01L 2224/37664	<administrative transfer to H10W 72/655 and H10W 72/652 simultaneously>
D	H01L 2224/37666	<administrative transfer to H10W 72/655 and H10W 72/652 simultaneously>
D	H01L 2224/37669	<administrative transfer to H10W 72/655 and H10W 72/652 simultaneously>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/3767	<administrative transfer to H10W 72/655 and H10W 72/652 simultaneously>
D	H01L 2224/37671	<administrative transfer to H10W 72/655 and H10W 72/652 simultaneously>
D	H01L 2224/37672	<administrative transfer to H10W 72/655 and H10W 72/652 simultaneously>
D	H01L 2224/37673	<administrative transfer to H10W 72/655 and H10W 72/652 simultaneously>
D	H01L 2224/37676	<administrative transfer to H10W 72/655 and H10W 72/652 simultaneously>
D	H01L 2224/37678	<administrative transfer to H10W 72/655 and H10W 72/652 simultaneously>
D	H01L 2224/37679	<administrative transfer to H10W 72/655 and H10W 72/652 simultaneously>
D	H01L 2224/3768	<administrative transfer to H10W 72/655 and H10W 72/652 simultaneously>
D	H01L 2224/37681	<administrative transfer to H10W 72/655 and H10W 72/652 simultaneously>
D	H01L 2224/37683	<administrative transfer to H10W 72/655 and H10W 72/652 simultaneously>
D	H01L 2224/37684	<administrative transfer to H10W 72/655 and H10W 72/652 simultaneously>
D	H01L 2224/37686	<administrative transfer to H10W 72/655 and H10W 72/653 simultaneously>
D	H01L 2224/37687	<administrative transfer to H10W 72/655 and H10W 72/653 simultaneously>
D	H01L 2224/37688	<administrative transfer to H10W 72/655 and H10W 72/653 simultaneously>
D	H01L 2224/3769	<administrative transfer to H10W 72/655 and H10W 72/653 simultaneously>
D	H01L 2224/37691	<administrative transfer to H10W 72/655 and H10W 72/653 simultaneously>
D	H01L 2224/37693	<administrative transfer to H10W 72/655 and H10W 72/653 simultaneously>
D	H01L 2224/37694	<administrative transfer to H10W 72/655 and H10W 72/653 simultaneously>
D	H01L 2224/37695	<administrative transfer to H10W 72/655 and H10W 72/653 simultaneously>
D	H01L 2224/37698	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/651 simultaneously>
D	H01L 2224/37699	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/651 simultaneously>
D	H01L 2224/377	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37701	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37705	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37709	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/37711	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37713	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37714	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37716	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37717	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37718	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/3772	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37723	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37724	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37738	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37739	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37744	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37747	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37749	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37755	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37757	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/3776	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37763	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37764	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37766	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37769	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/3777	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37771	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37772	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37773	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/37776	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37778	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37779	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/3778	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37781	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37783	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37784	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37786	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/653 simultaneously>
D	H01L 2224/37787	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/653 simultaneously>
D	H01L 2224/37788	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/653 simultaneously>
D	H01L 2224/3779	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/653 simultaneously>
D	H01L 2224/37791	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/653 simultaneously>
D	H01L 2224/37793	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/653 simultaneously>
D	H01L 2224/37794	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/653 simultaneously>
D	H01L 2224/37795	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/653 simultaneously>
D	H01L 2224/37798	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/651 simultaneously>
D	H01L 2224/37799	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/651 simultaneously>
D	H01L 2224/378	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37801	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37805	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37809	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37811	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37813	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37814	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37816	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/37817	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37818	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/3782	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37823	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37824	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37838	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37839	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37844	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37847	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37849	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37855	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37857	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/3786	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37863	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37864	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37866	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37869	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/3787	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37871	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37872	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37873	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37876	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37878	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37879	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/3788	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/37881	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37883	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37884	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37886	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/653 simultaneously>
D	H01L 2224/37887	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/653 simultaneously>
D	H01L 2224/37888	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/653 simultaneously>
D	H01L 2224/3789	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/653 simultaneously>
D	H01L 2224/37891	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/653 simultaneously>
D	H01L 2224/37893	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/653 simultaneously>
D	H01L 2224/37894	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/653 simultaneously>
D	H01L 2224/37895	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/653 simultaneously>
D	H01L 2224/37898	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/651 simultaneously>
D	H01L 2224/37899	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/651 simultaneously>
D	H01L 2224/379	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37901	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37905	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37909	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37911	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37913	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37914	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37916	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37917	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37918	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/3792	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37923	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>

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Type*	<u>From CPC Symbol (existing)</u>	<u>To CPC Symbol(s)</u>
D	H01L 2224/37924	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37938	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37939	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37944	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37947	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37949	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37955	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37957	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/3796	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37963	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37964	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37966	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37969	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/3797	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37971	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37972	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37973	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37976	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37978	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37979	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/3798	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37981	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37983	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37984	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/652 simultaneously>
D	H01L 2224/37986	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/653 simultaneously>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/37987	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/653 simultaneously>
D	H01L 2224/37988	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/653 simultaneously>
D	H01L 2224/3799	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/653 simultaneously>
D	H01L 2224/37991	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/653 simultaneously>
D	H01L 2224/37993	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/653 simultaneously>
D	H01L 2224/37994	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/653 simultaneously>
D	H01L 2224/37995	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/653 simultaneously>
D	H01L 2224/37998	<administrative transfer to H10W 72/655, H10W 72/625 and H10W 72/653 simultaneously>
D	H01L 2224/37999	<administrative transfer to H10W 72/655 and H10W 72/625 simultaneously>
D	H01L 2224/38	<administrative transfer to H10W 72/60>
D	H01L 2224/39	<administrative transfer to H10W 72/60 and H10W 72/07651 simultaneously>
D	H01L 2224/40	<administrative transfer to H10W 72/60 and H10W 72/07651 simultaneously>
D	H01L 2224/4001	<administrative transfer to H10W 72/07652 and H10W 72/621 simultaneously>
D	H01L 2224/4005	<administrative transfer to H10W 72/07653 and H10W 72/631 simultaneously>
D	H01L 2224/4007	<administrative transfer to H10W 72/07653 and H10W 72/631 simultaneously>
D	H01L 2224/4009	<administrative transfer to H10W 72/07653 and H10W 72/631 simultaneously>
D	H01L 2224/40091	<administrative transfer to H10W 72/07653>
D	H01L 2224/40095	<administrative transfer to H10W 72/07653>
D	H01L 2224/401	<administrative transfer to H10W 72/647>
D	H01L 2224/40101	<administrative transfer to H10W 72/647>
D	H01L 2224/40105	<administrative transfer to H10W 72/647>
D	H01L 2224/40106	<administrative transfer to H10W 72/642>
D	H01L 2224/40108	<administrative transfer to H10W 72/643>
D	H01L 2224/40111	<administrative transfer to H10W 72/07654>
D	H01L 2224/4013	<administrative transfer to H10W 72/644>
D	H01L 2224/40132	<administrative transfer to H10W 72/644>
D	H01L 2224/40135	<administrative transfer to H10W 90/761>
D	H01L 2224/40137	<administrative transfer to H10W 90/763>
D	H01L 2224/40139	<administrative transfer to H10W 90/763>
D	H01L 2224/40141	<administrative transfer to H10W 90/761>
D	H01L 2224/40145	<administrative transfer to H10W 90/762>
D	H01L 2224/40147	<administrative transfer to H10W 90/762>
D	H01L 2224/40151	<administrative transfer to H10W 90/761>
D	H01L 2224/40153	<administrative transfer to H10W 90/761>
D	H01L 2224/40155	<administrative transfer to H10W 90/765>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/40157	<administrative transfer to H10W 90/765>
D	H01L 2224/40158	<administrative transfer to H10W 90/765>
D	H01L 2224/40159	<administrative transfer to H10W 90/765>
D	H01L 2224/4016	<administrative transfer to H10W 90/765>
D	H01L 2224/40163	<administrative transfer to H10W 90/765>
D	H01L 2224/40165	<administrative transfer to H10W 90/765>
D	H01L 2224/40175	<administrative transfer to H10W 90/767>
D	H01L 2224/40177	<administrative transfer to H10W 90/767>
D	H01L 2224/40178	<administrative transfer to H10W 90/767>
D	H01L 2224/40179	<administrative transfer to H10W 90/767>
D	H01L 2224/40183	<administrative transfer to H10W 90/767>
D	H01L 2224/40195	<administrative transfer to H10W 90/769>
D	H01L 2224/40221	<administrative transfer to H10W 90/761>
D	H01L 2224/40225	<administrative transfer to H10W 90/764>
D	H01L 2224/40227	<administrative transfer to H10W 90/764>
D	H01L 2224/40228	<administrative transfer to H10W 90/764>
D	H01L 2224/40229	<administrative transfer to H10W 90/764>
D	H01L 2224/4023	<administrative transfer to H10W 90/764>
D	H01L 2224/40233	<administrative transfer to H10W 90/764>
D	H01L 2224/40235	<administrative transfer to H10W 90/764>
D	H01L 2224/40237	<administrative transfer to H10W 90/764>
D	H01L 2224/4024	<administrative transfer to H10W 90/764>
D	H01L 2224/40245	<administrative transfer to H10W 90/766>
D	H01L 2224/40247	<administrative transfer to H10W 90/766>
D	H01L 2224/40248	<administrative transfer to H10W 90/766>
D	H01L 2224/40249	<administrative transfer to H10W 90/766>
D	H01L 2224/40253	<administrative transfer to H10W 90/766>
D	H01L 2224/40257	<administrative transfer to H10W 90/766>
D	H01L 2224/4026	<administrative transfer to H10W 90/766>
D	H01L 2224/40265	<administrative transfer to H10W 90/768>
D	H01L 2224/404	<administrative transfer to H10W 72/60>
D	H01L 2224/4046	<administrative transfer to H10W 72/07653>
D	H01L 2224/40475	<administrative transfer to H10W 72/646>
D	H01L 2224/40477	<administrative transfer to H10W 72/646>
D	H01L 2224/40479	<administrative transfer to H10W 72/646>
D	H01L 2224/4048	<administrative transfer to H10W 72/646>
D	H01L 2224/40484	<administrative transfer to H10W 72/646>
D	H01L 2224/40486	<administrative transfer to H10W 72/646>
D	H01L 2224/40487	<administrative transfer to H10W 72/646>
D	H01L 2224/40491	<administrative transfer to H10W 72/646>
D	H01L 2224/40496	<administrative transfer to H10W 72/646>
D	H01L 2224/40499	<administrative transfer to H10W 72/646>
D	H01L 2224/405	<administrative transfer to H10W 72/07655>
D	H01L 2224/40505	<administrative transfer to H10W 72/07655>
D	H01L 2224/40506	<administrative transfer to H10W 72/07655 and H10W 72/6524 simultaneously>
D	H01L 2224/40507	<administrative transfer to H10W 72/6528>
D	H01L 2224/4051	<administrative transfer to H10W 72/07655>
D	H01L 2224/4052	<administrative transfer to H10W 72/07655>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/4099	<administrative transfer to H10W 72/681>
D	H01L 2224/40991	<administrative transfer to H10W 72/681>
D	H01L 2224/40992	<administrative transfer to H10W 72/683>
D	H01L 2224/40993	<administrative transfer to H10W 72/685>
D	H01L 2224/40996	<administrative transfer to H10W 72/681>
D	H01L 2224/40997	<administrative transfer to H10W 72/683>
D	H01L 2224/40998	<administrative transfer to H10W 72/685>
D	H01L 2224/41	<administrative transfer to H10W 72/60>
D	H01L 2224/4101	<administrative transfer to H10W 72/627 and H10W 72/07652 simultaneously>
D	H01L 2224/4103	<administrative transfer to H10W 72/627 and H10W 72/07652 simultaneously>
D	H01L 2224/4105	<administrative transfer to H10W 72/631>
D	H01L 2224/41051	<administrative transfer to H10W 72/637>
D	H01L 2224/41052	<administrative transfer to H10W 72/637>
D	H01L 2224/411	<administrative transfer to H10W 72/647>
D	H01L 2224/41105	<administrative transfer to H10W 72/647>
D	H01L 2224/41107	<administrative transfer to H10W 72/647>
D	H01L 2224/41109	<administrative transfer to H10W 72/647>
D	H01L 2224/4111	<administrative transfer to H10W 72/647 and H10W 72/6478 simultaneously>
D	H01L 2224/41111	<administrative transfer to H10W 72/647 and H10W 72/6478 simultaneously>
D	H01L 2224/41112	<administrative transfer to H10W 72/647 and H10W 72/6478 simultaneously>
D	H01L 2224/41113	<administrative transfer to H10W 72/647 and H10W 72/6478 simultaneously>
D	H01L 2224/4112	<administrative transfer to H10W 72/647 and H10W 72/07654 simultaneously>
D	H01L 2224/4117	<administrative transfer to H10W 72/647 and H10W 72/07654 simultaneously>
D	H01L 2224/41171	<administrative transfer to H10W 72/647 and H10W 72/643 simultaneously>
D	H01L 2224/41173	<administrative transfer to H10W 72/647 and H10W 72/643 simultaneously>
D	H01L 2224/41174	<administrative transfer to H10W 72/647 and H10W 72/07654 simultaneously>
D	H01L 2224/41175	<administrative transfer to H10W 72/647 and H10W 72/642 simultaneously>
D	H01L 2224/41176	<administrative transfer to H10W 72/647 and H10W 72/642 simultaneously>
D	H01L 2224/41177	<administrative transfer to H10W 72/647 and H10W 72/07654 simultaneously>
D	H01L 2224/41179	<administrative transfer to H10W 72/647 and H10W 72/07654 simultaneously>
D	H01L 2224/4118	<administrative transfer to H10W 72/647 and H10W 72/07654 simultaneously>
D	H01L 2224/414	<administrative transfer to H10W 72/60>
D	H01L 2224/4141	<administrative transfer to H10W 72/647 and H10W 72/646 simultaneously>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/41421	<administrative transfer to H10W 72/647 and H10W 72/646 simultaneously>
D	H01L 2224/41422	<administrative transfer to H10W 72/647 and H10W 72/646 simultaneously>
D	H01L 2224/4143	<administrative transfer to H10W 72/647 and H10W 72/07654 simultaneously>
D	H01L 2224/415	<administrative transfer to H10W 72/07655>
D	H01L 2224/41505	<administrative transfer to H10W 72/07655 and H10W 72/657 simultaneously>
D	H01L 2224/42	<administrative transfer to H10W 72/50>
D	H01L 2224/43	<administrative transfer to H10W 72/015>
D	H01L 2224/43001	<administrative transfer to H10W 72/01504>
D	H01L 2224/431	<administrative transfer to H10W 72/015>
D	H01L 2224/4312	<administrative transfer to H10W 72/01515>
D	H01L 2224/43125	<administrative transfer to H10W 72/01515>
D	H01L 2224/432	<administrative transfer to H10W 72/015>
D	H01L 2224/4321	<administrative transfer to H10W 72/01551>
D	H01L 2224/435	<administrative transfer to H10W 72/01561>
D	H01L 2224/4351	<administrative transfer to H10W 72/01561>
D	H01L 2224/4352	<administrative transfer to H10W 72/01561>
D	H01L 2224/437	<administrative transfer to H10W 72/015>
D	H01L 2224/438	<administrative transfer to H10W 72/015>
D	H01L 2224/4381	<administrative transfer to H10W 72/01571>
D	H01L 2224/4382	<administrative transfer to H10W 72/01515>
D	H01L 2224/43821	<administrative transfer to H10W 72/01515>
D	H01L 2224/43822	<administrative transfer to H10W 72/01515>
D	H01L 2224/43823	<administrative transfer to H10W 72/01515>
D	H01L 2224/43824	<administrative transfer to H10W 72/01515>
D	H01L 2224/43825	<administrative transfer to H10W 72/01515>
D	H01L 2224/43826	<administrative transfer to H10W 72/01515>
D	H01L 2224/43827	<administrative transfer to H10W 72/01515>
D	H01L 2224/4383	<administrative transfer to H10W 72/01551>
D	H01L 2224/43831	<administrative transfer to H10W 72/01553>
D	H01L 2224/43847	<administrative transfer to H10W 72/01561>
D	H01L 2224/43848	<administrative transfer to H10W 72/01565>
D	H01L 2224/43985	<administrative transfer to H10W 72/015>
D	H01L 2224/43986	<administrative transfer to H10W 72/015>
D	H01L 2224/44	<administrative transfer to H10W 72/50>
D	H01L 2224/45	<administrative transfer to H10W 72/50>
D	H01L 2224/45001	<administrative transfer to H10W 72/50>
D	H01L 2224/45005	<administrative transfer to H10W 72/521>
D	H01L 2224/4501	<administrative transfer to H10W 72/531>
D	H01L 2224/45012	<administrative transfer to H10W 72/533>
D	H01L 2224/45013	<administrative transfer to H10W 72/533>
D	H01L 2224/45014	<administrative transfer to H10W 72/534>
D	H01L 2224/45015	<no transfer>
D	H01L 2224/45016	<administrative transfer to H10W 72/533>
D	H01L 2224/4502	<administrative transfer to H10W 72/541>
D	H01L 2224/45025	<administrative transfer to H10W 72/524>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/45026	<administrative transfer to H10W 72/524>
D	H01L 2224/45028	<administrative transfer to H10W 72/524>
D	H01L 2224/4503	<administrative transfer to H10W 72/522>
D	H01L 2224/45032	<administrative transfer to H10W 72/522>
D	H01L 2224/45033	<administrative transfer to H10W 72/522>
D	H01L 2224/45034	<administrative transfer to H10W 72/522>
D	H01L 2224/45099	<administrative transfer to H10W 72/551>
D	H01L 2224/451	<administrative transfer to H10W 72/552>
D	H01L 2224/45101	<administrative transfer to H10W 72/552>
D	H01L 2224/45105	<administrative transfer to H10W 72/552>
D	H01L 2224/45109	<administrative transfer to H10W 72/552>
D	H01L 2224/45111	<administrative transfer to H10W 72/552>
D	H01L 2224/45113	<administrative transfer to H10W 72/552>
D	H01L 2224/45114	<administrative transfer to H10W 72/552>
D	H01L 2224/45116	<administrative transfer to H10W 72/552>
D	H01L 2224/45117	<administrative transfer to H10W 72/552>
D	H01L 2224/45118	<administrative transfer to H10W 72/552>
D	H01L 2224/4512	<administrative transfer to H10W 72/552>
D	H01L 2224/45123	<administrative transfer to H10W 72/552>
D	H01L 2224/45124	<administrative transfer to H10W 72/5524>
D	H01L 2224/45138	<administrative transfer to H10W 72/552>
D	H01L 2224/45139	<administrative transfer to H10W 72/552>
D	H01L 2224/45144	<administrative transfer to H10W 72/5522>
D	H01L 2224/45147	<administrative transfer to H10W 72/5525>
D	H01L 2224/45149	<administrative transfer to H10W 72/552>
D	H01L 2224/45155	<administrative transfer to H10W 72/552>
D	H01L 2224/45157	<administrative transfer to H10W 72/552>
D	H01L 2224/4516	<administrative transfer to H10W 72/552>
D	H01L 2224/45163	<administrative transfer to H10W 72/552>
D	H01L 2224/45164	<administrative transfer to H10W 72/552>
D	H01L 2224/45166	<administrative transfer to H10W 72/552>
D	H01L 2224/45169	<administrative transfer to H10W 72/552>
D	H01L 2224/4517	<administrative transfer to H10W 72/552>
D	H01L 2224/45171	<administrative transfer to H10W 72/552>
D	H01L 2224/45172	<administrative transfer to H10W 72/552>
D	H01L 2224/45173	<administrative transfer to H10W 72/552>
D	H01L 2224/45176	<administrative transfer to H10W 72/552>
D	H01L 2224/45178	<administrative transfer to H10W 72/552>
D	H01L 2224/45179	<administrative transfer to H10W 72/552>
D	H01L 2224/4518	<administrative transfer to H10W 72/552>
D	H01L 2224/45181	<administrative transfer to H10W 72/552>
D	H01L 2224/45183	<administrative transfer to H10W 72/552>
D	H01L 2224/45184	<administrative transfer to H10W 72/552>
D	H01L 2224/45186	<administrative transfer to H10W 72/553>
D	H01L 2224/45187	<administrative transfer to H10W 72/553>
D	H01L 2224/45188	<administrative transfer to H10W 72/553>
D	H01L 2224/4519	<administrative transfer to H10W 72/553>
D	H01L 2224/45191	<administrative transfer to H10W 72/553>
D	H01L 2224/45193	<administrative transfer to H10W 72/553>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/45194	<administrative transfer to H10W 72/553>
D	H01L 2224/45195	<administrative transfer to H10W 72/553>
D	H01L 2224/45198	<administrative transfer to H10W 72/525 and H10W 72/551 simultaneously>
D	H01L 2224/45199	<administrative transfer to H10W 72/525 and H10W 72/551 simultaneously>
D	H01L 2224/452	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45201	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45205	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45209	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45211	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45213	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45214	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45216	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45217	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45218	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/4522	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45223	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45224	<administrative transfer to H10W 72/525 and H10W 72/5524 simultaneously>
D	H01L 2224/45238	H10W 72/525, H10W 72/552
D	H01L 2224/45239	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45244	<administrative transfer to H10W 72/525 and H10W 72/5522 simultaneously>
D	H01L 2224/45247	<administrative transfer to H10W 72/525 and H10W 72/5525 simultaneously>
D	H01L 2224/45249	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45255	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45257	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/4526	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45263	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/45264	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45266	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45269	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/4527	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45271	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45272	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45273	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45276	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45278	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45279	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/4528	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45281	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45283	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45284	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45286	<administrative transfer to H10W 72/525 and H10W 72/553 simultaneously>
D	H01L 2224/45287	<administrative transfer to H10W 72/525 and H10W 72/553 simultaneously>
D	H01L 2224/45288	<administrative transfer to H10W 72/525 and H10W 72/553 simultaneously>
D	H01L 2224/4529	<administrative transfer to H10W 72/525 and H10W 72/553 simultaneously>
D	H01L 2224/45291	<administrative transfer to H10W 72/525 and H10W 72/553 simultaneously>
D	H01L 2224/45293	<administrative transfer to H10W 72/525 and H10W 72/553 simultaneously>
D	H01L 2224/45294	<administrative transfer to H10W 72/525 and H10W 72/553 simultaneously>
D	H01L 2224/45295	<administrative transfer to H10W 72/525 and H10W 72/553 simultaneously>
D	H01L 2224/45298	<administrative transfer to H10W 72/525>
D	H01L 2224/45299	<administrative transfer to H10W 72/525>
D	H01L 2224/453	H10W 72/525, H10W 72/552
D	H01L 2224/45301	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/45305	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45309	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45311	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45313	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45314	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45316	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45317	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45318	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/4532	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45323	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45324	<administrative transfer to H10W 72/525 and H10W 72/5524 simultaneously>
D	H01L 2224/45338	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45339	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45344	<administrative transfer to H10W 72/525 and H10W 72/5522 simultaneously>
D	H01L 2224/45347	<administrative transfer to H10W 72/525 and H10W 72/5525 simultaneously>
D	H01L 2224/45349	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45355	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45357	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/4536	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45363	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45364	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45366	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45369	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/4537	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45371	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/45372	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45373	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45376	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45378	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45379	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/4538	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45381	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45383	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45384	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45386	<administrative transfer to H10W 72/525 and H10W 72/553 simultaneously>
D	H01L 2224/45387	<administrative transfer to H10W 72/525 and H10W 72/553 simultaneously>
D	H01L 2224/45388	<administrative transfer to H10W 72/525 and H10W 72/553 simultaneously>
D	H01L 2224/4539	<administrative transfer to H10W 72/525 and H10W 72/553 simultaneously>
D	H01L 2224/45391	<administrative transfer to H10W 72/525 and H10W 72/553 simultaneously>
D	H01L 2224/45393	<administrative transfer to H10W 72/525 and H10W 72/553 simultaneously>
D	H01L 2224/45394	<administrative transfer to H10W 72/525 and H10W 72/553 simultaneously>
D	H01L 2224/45395	<administrative transfer to H10W 72/525 and H10W 72/553 simultaneously>
D	H01L 2224/45398	<administrative transfer to H10W 72/525 and H10W 72/553 simultaneously>
D	H01L 2224/45399	<administrative transfer to H10W 72/525 and H10W 72/551 simultaneously>
D	H01L 2224/454	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45401	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45405	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45409	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45411	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45413	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/45414	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45416	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45417	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45418	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/4542	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45423	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45424	<administrative transfer to H10W 72/525 and H10W 72/5524 simultaneously>
D	H01L 2224/45438	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45439	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45444	<administrative transfer to H10W 72/525 and H10W 72/5522 simultaneously>
D	H01L 2224/45447	<administrative transfer to H10W 72/525 and H10W 72/5525 simultaneously>
D	H01L 2224/45449	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45455	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45457	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/4546	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45463	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45464	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45466	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45469	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/4547	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45471	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45472	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45473	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45476	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45478	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/45479	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/4548	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45481	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45483	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45484	<administrative transfer to H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45486	<administrative transfer to H10W 72/525 and H10W 72/553 simultaneously>
D	H01L 2224/45487	<administrative transfer to H10W 72/525 and H10W 72/553 simultaneously>
D	H01L 2224/45488	<administrative transfer to H10W 72/525 and H10W 72/553 simultaneously>
D	H01L 2224/4549	<administrative transfer to H10W 72/525 and H10W 72/553 simultaneously>
D	H01L 2224/45491	<administrative transfer to H10W 72/525 and H10W 72/553 simultaneously>
D	H01L 2224/45493	<administrative transfer to H10W 72/525 and H10W 72/553 simultaneously>
D	H01L 2224/45494	<administrative transfer to H10W 72/525 and H10W 72/553 simultaneously>
D	H01L 2224/45495	<administrative transfer to H10W 72/525 and H10W 72/553 simultaneously>
D	H01L 2224/45498	<administrative transfer to H10W 72/525 and H10W 72/553 simultaneously>
D	H01L 2224/45499	<administrative transfer to H10W 72/525>
D	H01L 2224/4554	<administrative transfer to H10W 72/522>
D	H01L 2224/45541	<administrative transfer to H10W 72/523>
D	H01L 2224/4555	<administrative transfer to H10W 72/535>
D	H01L 2224/4556	<administrative transfer to H10W 72/543>
D	H01L 2224/45565	<administrative transfer to H10W 72/522>
D	H01L 2224/4557	<administrative transfer to H10W 72/523>
D	H01L 2224/45572	<administrative transfer to H10W 72/523>
D	H01L 2224/45573	<administrative transfer to H10W 72/523>
D	H01L 2224/45574	<administrative transfer to H10W 72/523>
D	H01L 2224/45576	<administrative transfer to H10W 72/523>
D	H01L 2224/45578	<administrative transfer to H10W 72/523>
D	H01L 2224/45599	<administrative transfer to H10W 72/555 and H10W 72/551 simultaneously>
D	H01L 2224/456	<administrative transfer to H10W 72/555 and H10W 72/552 simultaneously>
D	H01L 2224/45601	<administrative transfer to H10W 72/555 and H10W 72/552 simultaneously>
D	H01L 2224/45605	<administrative transfer to H10W 72/555 and H10W 72/552 simultaneously>
D	H01L 2224/45609	<administrative transfer to H10W 72/555 and H10W 72/552 simultaneously>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/45611	<administrative transfer to H10W 72/555 and H10W 72/552 simultaneously>
D	H01L 2224/45613	<administrative transfer to H10W 72/555 and H10W 72/552 simultaneously>
D	H01L 2224/45614	<administrative transfer to H10W 72/555 and H10W 72/552 simultaneously>
D	H01L 2224/45616	<administrative transfer to H10W 72/555 and H10W 72/552 simultaneously>
D	H01L 2224/45617	<administrative transfer to H10W 72/555 and H10W 72/552 simultaneously>
D	H01L 2224/45618	<administrative transfer to H10W 72/555 and H10W 72/552 simultaneously>
D	H01L 2224/4562	<administrative transfer to H10W 72/555 and H10W 72/552 simultaneously>
D	H01L 2224/45623	<administrative transfer to H10W 72/555 and H10W 72/552 simultaneously>
D	H01L 2224/45624	<administrative transfer to H10W 72/555 and H10W 72/5524 simultaneously>
D	H01L 2224/45638	<administrative transfer to H10W 72/555 and H10W 72/552 simultaneously>
D	H01L 2224/45639	<administrative transfer to H10W 72/555 and H10W 72/552 simultaneously>
D	H01L 2224/45644	<administrative transfer to H10W 72/555 and H10W 72/5522 simultaneously>
D	H01L 2224/45647	<administrative transfer to H10W 72/555 and H10W 72/5525 simultaneously>
D	H01L 2224/45649	<administrative transfer to H10W 72/555 and H10W 72/552 simultaneously>
D	H01L 2224/45655	<administrative transfer to H10W 72/555 and H10W 72/552 simultaneously>
D	H01L 2224/45657	<administrative transfer to H10W 72/555 and H10W 72/552 simultaneously>
D	H01L 2224/4566	<administrative transfer to H10W 72/555 and H10W 72/552 simultaneously>
D	H01L 2224/45663	<administrative transfer to H10W 72/555 and H10W 72/552 simultaneously>
D	H01L 2224/45664	<administrative transfer to H10W 72/555 and H10W 72/552 simultaneously>
D	H01L 2224/45666	<administrative transfer to H10W 72/555 and H10W 72/552 simultaneously>
D	H01L 2224/45669	<administrative transfer to H10W 72/555 and H10W 72/552 simultaneously>
D	H01L 2224/4567	<administrative transfer to H10W 72/555 and H10W 72/552 simultaneously>
D	H01L 2224/45671	<administrative transfer to H10W 72/555 and H10W 72/552 simultaneously>
D	H01L 2224/45672	<administrative transfer to H10W 72/555 and H10W 72/552 simultaneously>
D	H01L 2224/45673	<administrative transfer to H10W 72/555 and H10W 72/552 simultaneously>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/45676	<administrative transfer to H10W 72/555 and H10W 72/552 simultaneously>
D	H01L 2224/45678	<administrative transfer to H10W 72/555 and H10W 72/552 simultaneously>
D	H01L 2224/45679	<administrative transfer to H10W 72/555 and H10W 72/552 simultaneously>
D	H01L 2224/4568	<administrative transfer to H10W 72/555 and H10W 72/552 simultaneously>
D	H01L 2224/45681	<administrative transfer to H10W 72/555 and H10W 72/552 simultaneously>
D	H01L 2224/45683	<administrative transfer to H10W 72/555 and H10W 72/552 simultaneously>
D	H01L 2224/45684	<administrative transfer to H10W 72/555 and H10W 72/552 simultaneously>
D	H01L 2224/45686	<administrative transfer to H10W 72/555 and H10W 72/553 simultaneously>
D	H01L 2224/45687	<administrative transfer to H10W 72/555 and H10W 72/553 simultaneously>
D	H01L 2224/45688	<administrative transfer to H10W 72/555 and H10W 72/553 simultaneously>
D	H01L 2224/4569	<administrative transfer to H10W 72/555 and H10W 72/553 simultaneously>
D	H01L 2224/45691	<administrative transfer to H10W 72/555 and H10W 72/553 simultaneously>
D	H01L 2224/45693	<administrative transfer to H10W 72/555 and H10W 72/553 simultaneously>
D	H01L 2224/45694	<administrative transfer to H10W 72/555 and H10W 72/553 simultaneously>
D	H01L 2224/45695	<administrative transfer to H10W 72/555 and H10W 72/553 simultaneously>
D	H01L 2224/45698	<administrative transfer to H10W 72/555 and H10W 72/525 simultaneously>
D	H01L 2224/45699	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/551 simultaneously>
D	H01L 2224/457	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45701	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45705	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45709	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45711	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45713	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45714	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45716	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/45717	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45718	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/4572	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45723	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45724	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45738	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45739	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45744	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45747	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45749	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45755	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45757	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/4576	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45763	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45764	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45766	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45769	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/4577	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45771	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45772	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45773	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45776	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45778	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45779	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/4578	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/45781	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45783	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45784	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45786	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/553 simultaneously>
D	H01L 2224/45787	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/553 simultaneously>
D	H01L 2224/45788	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/553 simultaneously>
D	H01L 2224/4579	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/553 simultaneously>
D	H01L 2224/45791	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/553 simultaneously>
D	H01L 2224/45793	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/553 simultaneously>
D	H01L 2224/45794	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/553 simultaneously>
D	H01L 2224/45795	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/553 simultaneously>
D	H01L 2224/45798	<administrative transfer to H10W 72/555 and H10W 72/525 simultaneously>
D	H01L 2224/45799	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/551 simultaneously>
D	H01L 2224/458	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45801	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45805	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45809	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45811	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45813	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45814	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45816	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45817	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45818	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/4582	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45823	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/45824	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/5524 simultaneously>
D	H01L 2224/45838	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45839	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45844	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/5522 simultaneously>
D	H01L 2224/45847	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/5525 simultaneously>
D	H01L 2224/45849	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45855	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45857	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/4586	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45863	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45864	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45866	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45869	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/4587	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45871	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45872	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45873	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45876	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45878	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45879	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/4588	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45881	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45883	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45884	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45886	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/553 simultaneously>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/45887	H10W 72/555, H10W 72/525, H10W 72/553
D	H01L 2224/45888	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/553 simultaneously>
D	H01L 2224/4589	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/553 simultaneously>
D	H01L 2224/45891	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/553 simultaneously>
D	H01L 2224/45893	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/553 simultaneously>
D	H01L 2224/45894	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/553 simultaneously>
D	H01L 2224/45895	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/553 simultaneously>
D	H01L 2224/45898	<administrative transfer to H10W 72/555 and H10W 72/525 simultaneously>
D	H01L 2224/45899	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/551 simultaneously>
D	H01L 2224/459	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45901	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45905	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45909	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45911	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45913	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45914	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45916	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45917	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45918	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/4592	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45923	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45924	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/5524 simultaneously>
D	H01L 2224/45938	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45939	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45944	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/5522 simultaneously>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/45947	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45949	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45955	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45957	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/4596	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45963	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45964	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45966	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45969	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/4597	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45971	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45972	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45973	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45976	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45978	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45979	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/4598	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45981	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45983	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45984	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/552 simultaneously>
D	H01L 2224/45986	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/553 simultaneously>
D	H01L 2224/45987	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/553 simultaneously>
D	H01L 2224/45988	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/553 simultaneously>
D	H01L 2224/4599	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/553 simultaneously>
D	H01L 2224/45991	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/553 simultaneously>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/45993	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/553 simultaneously>
D	H01L 2224/45994	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/553 simultaneously>
D	H01L 2224/45995	<administrative transfer to H10W 72/555, H10W 72/525 and H10W 72/553 simultaneously>
D	H01L 2224/45998	<administrative transfer to H10W 72/555 and H10W 72/525 simultaneously>
D	H01L 2224/45999	<administrative transfer to H10W 72/555 and H10W 72/525 simultaneously>
D	H01L 2224/46	<administrative transfer to H10W 72/50>
D	H01L 2224/47	<administrative transfer to H10W 72/07551 and H10W 72/50 simultaneously>
D	H01L 2224/48	<administrative transfer to H10W 72/07551 and H10W 72/50 simultaneously>
D	H01L 2224/4801	<administrative transfer to H10W 72/07552 and H10W 72/521 simultaneously>
D	H01L 2224/48011	<administrative transfer to H10W 72/07552 and H10W 72/521 simultaneously>
D	H01L 2224/4805	<administrative transfer to H10W 72/07553 and H10W 72/531 simultaneously>
D	H01L 2224/4807	<administrative transfer to H10W 72/07553 and H10W 72/531 simultaneously>
D	H01L 2224/4809	<administrative transfer to H10W 72/07553 and H10W 72/531 simultaneously>
D	H01L 2224/48091	<no transfer>
D	H01L 2224/48092	<administrative transfer to H10W 72/5368>
D	H01L 2224/48095	<administrative transfer to H10W 72/5366>
D	H01L 2224/48096	<administrative transfer to H10W 72/5366>
D	H01L 2224/48097	<administrative transfer to H10W 72/5366>
D	H01L 2224/481	<administrative transfer to H10W 72/07554>
D	H01L 2224/48101	<administrative transfer to H10W 72/07554>
D	H01L 2224/48105	<administrative transfer to H10W 72/07554>
D	H01L 2224/48106	<administrative transfer to H10W 72/5445>
D	H01L 2224/48108	<administrative transfer to H10W 72/5449>
D	H01L 2224/4811	<administrative transfer to H10W 72/07554>
D	H01L 2224/48111	<administrative transfer to H10W 72/07554>
D	H01L 2224/4813	<administrative transfer to H10W 72/5453>
D	H01L 2224/48132	<administrative transfer to H10W 72/5453>
D	H01L 2224/48135	<administrative transfer to H10W 90/751>
D	H01L 2224/48137	<administrative transfer to H10W 90/753>
D	H01L 2224/48138	<administrative transfer to H10W 90/753>
D	H01L 2224/48139	<administrative transfer to H10W 90/753>
D	H01L 2224/4814	<administrative transfer to H10W 90/753>
D	H01L 2224/48141	<administrative transfer to H10W 90/751>
D	H01L 2224/48145	<administrative transfer to H10W 90/752>
D	H01L 2224/48147	<administrative transfer to H10W 90/752>
D	H01L 2224/48148	<administrative transfer to H10W 90/752>
D	H01L 2224/48149	<administrative transfer to H10W 90/752>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/48151	<administrative transfer to H10W 90/751>
D	H01L 2224/48153	<administrative transfer to H10W 90/751>
D	H01L 2224/48155	<administrative transfer to H10W 90/755>
D	H01L 2224/48157	<administrative transfer to H10W 90/755>
D	H01L 2224/48158	<administrative transfer to H10W 90/755>
D	H01L 2224/48159	<administrative transfer to H10W 90/755>
D	H01L 2224/4816	<administrative transfer to H10W 90/755>
D	H01L 2224/48163	<administrative transfer to H10W 90/755>
D	H01L 2224/48165	<administrative transfer to H10W 90/755>
D	H01L 2224/48175	<administrative transfer to H10W 90/755>
D	H01L 2224/48177	<administrative transfer to H10W 90/755>
D	H01L 2224/48178	<administrative transfer to H10W 90/755>
D	H01L 2224/48179	<administrative transfer to H10W 90/755>
D	H01L 2224/48183	<administrative transfer to H10W 90/755>
D	H01L 2224/48195	<administrative transfer to H10W 90/759>
D	H01L 2224/48221	<administrative transfer to H10W 90/751>
D	H01L 2224/48225	<administrative transfer to H10W 90/754>
D	H01L 2224/48227	<administrative transfer to H10W 90/754>
D	H01L 2224/48228	<administrative transfer to H10W 90/754>
D	H01L 2224/48229	<administrative transfer to H10W 90/754>
D	H01L 2224/4823	<administrative transfer to H10W 90/754>
D	H01L 2224/48233	<administrative transfer to H10W 90/754>
D	H01L 2224/48235	<administrative transfer to H10W 90/754>
D	H01L 2224/48237	<administrative transfer to H10W 90/754>
D	H01L 2224/4824	<administrative transfer to H10W 90/754>
D	H01L 2224/48245	<administrative transfer to H10W 90/756>
D	H01L 2224/48247	<administrative transfer to H10W 90/756>
D	H01L 2224/48248	<administrative transfer to H10W 90/756>
D	H01L 2224/48249	<administrative transfer to H10W 90/756>
D	H01L 2224/48253	<administrative transfer to H10W 90/756>
D	H01L 2224/48257	<administrative transfer to H10W 90/756>
D	H01L 2224/4826	<administrative transfer to H10W 90/756>
D	H01L 2224/48265	<administrative transfer to H10W 90/758>
D	H01L 2224/484	<administrative transfer to H10W 72/50>
D	H01L 2224/4845	<administrative transfer to H10W 72/536>
D	H01L 2224/48451	<administrative transfer to H10W 72/536>
D	H01L 2224/48453	<administrative transfer to H10W 72/536>
D	H01L 2224/48455	<administrative transfer to H10W 72/5363>
D	H01L 2224/48456	<administrative transfer to H10W 72/5363>
D	H01L 2224/48458	<administrative transfer to H10W 72/5363>
D	H01L 2224/4846	<administrative transfer to H10W 72/5438>
D	H01L 2224/48463	<administrative transfer to H10W 72/536>
D	H01L 2224/48464	<administrative transfer to H10W 72/536>
D	H01L 2224/48465	<administrative transfer to H10W 72/536 and H10W 72/5363 simultaneously>
D	H01L 2224/4847	<administrative transfer to H10W 72/5363>
D	H01L 2224/48471	<administrative transfer to H10W 72/536 and H10W 72/5363 simultaneously>
D	H01L 2224/48472	<administrative transfer to H10W 72/5363>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/48475	<administrative transfer to H10W 72/5434>
D	H01L 2224/48476	<administrative transfer to H10W 72/5434>
D	H01L 2224/48477	<administrative transfer to H10W 72/5434>
D	H01L 2224/48478	<administrative transfer to H10W 72/5434>
D	H01L 2224/48479	<administrative transfer to H10W 72/5434>
D	H01L 2224/4848	<administrative transfer to H10W 72/5434>
D	H01L 2224/48481	<administrative transfer to H10W 72/5434>
D	H01L 2224/48482	<administrative transfer to H10W 72/5434>
D	H01L 2224/48483	<administrative transfer to H10W 72/5434>
D	H01L 2224/48484	<administrative transfer to H10W 72/5434>
D	H01L 2224/48485	<administrative transfer to H10W 72/5434>
D	H01L 2224/48486	<administrative transfer to H10W 72/5434>
D	H01L 2224/48487	<administrative transfer to H10W 72/5434>
D	H01L 2224/48488	<administrative transfer to H10W 72/5434>
D	H01L 2224/48489	<administrative transfer to H10W 72/5434>
D	H01L 2224/4849	<administrative transfer to H10W 72/5434>
D	H01L 2224/48491	<administrative transfer to H10W 72/5434>
D	H01L 2224/48496	<administrative transfer to H10W 72/5434>
D	H01L 2224/48499	<administrative transfer to H10W 72/5434>
D	H01L 2224/485	<administrative transfer to H10W 72/07555 and H10W 72/551 simultaneously>
D	H01L 2224/48505	<administrative transfer to H10W 72/07555 and H10W 72/551 simultaneously>
D	H01L 2224/48506	<administrative transfer to H10W 72/07555 and H10W 72/5527 simultaneously>
D	H01L 2224/48507	<administrative transfer to H10W 72/07555 and H10W 72/5528 simultaneously>
D	H01L 2224/4851	<administrative transfer to H10W 72/07555 and H10W 72/551 simultaneously>
D	H01L 2224/48511	<administrative transfer to H10W 72/07555 and H10W 72/551 simultaneously>
D	H01L 2224/4852	<administrative transfer to H10W 72/07555 and H10W 72/551 simultaneously>
D	H01L 2224/48599	<administrative transfer to H10W 72/59 and H10W 72/5522 simultaneously>
D	H01L 2224/486	<administrative transfer to H10W 72/59, H10W 72/5522 and H10W 72/952 simultaneously>
D	H01L 2224/48601	<administrative transfer to H10W 72/59, H10W 72/5522 and H10W 72/952 simultaneously>
D	H01L 2224/48605	<administrative transfer to H10W 72/59, H10W 72/5522 and H10W 72/952 simultaneously>
D	H01L 2224/48609	<administrative transfer to H10W 72/59, H10W 72/5522 and H10W 72/952 simultaneously>
D	H01L 2224/48611	<administrative transfer to H10W 72/59, H10W 72/5522 and H10W 72/952 simultaneously>
D	H01L 2224/48613	<administrative transfer to H10W 72/59, H10W 72/5522 and H10W 72/952 simultaneously>
D	H01L 2224/48614	<administrative transfer to H10W 72/59, H10W 72/5522 and H10W 72/952 simultaneously>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/48616	<administrative transfer to H10W 72/59, H10W 72/5522 and H10W 72/952 simultaneously>
D	H01L 2224/48617	<administrative transfer to H10W 72/59, H10W 72/5522 and H10W 72/952 simultaneously>
D	H01L 2224/48618	<administrative transfer to H10W 72/59, H10W 72/5522 and H10W 72/952 simultaneously>
D	H01L 2224/4862	<administrative transfer to H10W 72/59, H10W 72/5522 and H10W 72/952 simultaneously>
D	H01L 2224/48623	<administrative transfer to H10W 72/59, H10W 72/5522 and H10W 72/952 simultaneously>
D	H01L 2224/48624	<administrative transfer to H10W 72/59, H10W 72/5522 and H10W 72/952 simultaneously>
D	H01L 2224/48638	<administrative transfer to H10W 72/59, H10W 72/5522 and H10W 72/952 simultaneously>
D	H01L 2224/48639	<administrative transfer to H10W 72/59, H10W 72/5522 and H10W 72/952 simultaneously>
D	H01L 2224/48644	<administrative transfer to H10W 72/59, H10W 72/5522 and H10W 72/952 simultaneously>
D	H01L 2224/48647	<administrative transfer to H10W 72/59, H10W 72/5522 and H10W 72/952 simultaneously>
D	H01L 2224/48649	<administrative transfer to H10W 72/59, H10W 72/5522 and H10W 72/952 simultaneously>
D	H01L 2224/48655	<administrative transfer to H10W 72/59, H10W 72/5522 and H10W 72/952 simultaneously>
D	H01L 2224/48657	<administrative transfer to H10W 72/59, H10W 72/5522 and H10W 72/952 simultaneously>
D	H01L 2224/4866	<administrative transfer to H10W 72/59, H10W 72/5522 and H10W 72/952 simultaneously>
D	H01L 2224/48663	<administrative transfer to H10W 72/59, H10W 72/5522 and H10W 72/952 simultaneously>
D	H01L 2224/48664	<administrative transfer to H10W 72/59, H10W 72/5522 and H10W 72/952 simultaneously>
D	H01L 2224/48666	<administrative transfer to H10W 72/59, H10W 72/5522 and H10W 72/952 simultaneously>
D	H01L 2224/48669	<administrative transfer to H10W 72/59, H10W 72/5522 and H10W 72/952 simultaneously>
D	H01L 2224/4867	<administrative transfer to H10W 72/59, H10W 72/5522 and H10W 72/952 simultaneously>
D	H01L 2224/48671	<administrative transfer to H10W 72/59, H10W 72/5522 and H10W 72/952 simultaneously>
D	H01L 2224/48672	<administrative transfer to H10W 72/59, H10W 72/5522 and H10W 72/952 simultaneously>
D	H01L 2224/48673	<administrative transfer to H10W 72/59, H10W 72/5522 and H10W 72/952 simultaneously>
D	H01L 2224/48678	<administrative transfer to H10W 72/59, H10W 72/5522 and H10W 72/952 simultaneously>
D	H01L 2224/48679	<administrative transfer to H10W 72/59, H10W 72/5522 and H10W 72/952 simultaneously>
D	H01L 2224/4868	<administrative transfer to H10W 72/59, H10W 72/5522 and H10W 72/952 simultaneously>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/48681	<administrative transfer to H10W 72/59, H10W 72/5522 and H10W 72/952 simultaneously>
D	H01L 2224/48683	<administrative transfer to H10W 72/59, H10W 72/5522 and H10W 72/952 simultaneously>
D	H01L 2224/48684	<administrative transfer to H10W 72/59, H10W 72/5522 and H10W 72/952 simultaneously>
D	H01L 2224/48686	<administrative transfer to H10W 72/59, H10W 72/5522 and H10W 72/953 simultaneously>
D	H01L 2224/48687	<administrative transfer to H10W 72/59, H10W 72/5522 and H10W 72/953 simultaneously>
D	H01L 2224/48688	<administrative transfer to H10W 72/59, H10W 72/5522 and H10W 72/953 simultaneously>
D	H01L 2224/4869	<administrative transfer to H10W 72/59, H10W 72/5522 and H10W 72/953 simultaneously>
D	H01L 2224/48691	<administrative transfer to H10W 72/59, H10W 72/5522 and H10W 72/953 simultaneously>
D	H01L 2224/48693	<administrative transfer to H10W 72/59, H10W 72/5522 and H10W 72/953 simultaneously>
D	H01L 2224/48694	<administrative transfer to H10W 72/59, H10W 72/5522 and H10W 72/953 simultaneously>
D	H01L 2224/48698	<administrative transfer to H10W 72/59, H10W 72/5522 and H10W 72/953 simultaneously>
D	H01L 2224/48699	<administrative transfer to H10W 72/59 and H10W 72/5524 simultaneously>
D	H01L 2224/487	<administrative transfer to H10W 72/59, H10W 72/5524 and H10W 72/952 simultaneously>
D	H01L 2224/48701	<administrative transfer to H10W 72/59, H10W 72/5524 and H10W 72/952 simultaneously>
D	H01L 2224/48705	<administrative transfer to H10W 72/59, H10W 72/5524 and H10W 72/952 simultaneously>
D	H01L 2224/48709	<administrative transfer to H10W 72/59, H10W 72/5524 and H10W 72/952 simultaneously>
D	H01L 2224/48711	<administrative transfer to H10W 72/59, H10W 72/5524 and H10W 72/952 simultaneously>
D	H01L 2224/48713	<administrative transfer to H10W 72/59, H10W 72/5524 and H10W 72/952 simultaneously>
D	H01L 2224/48714	<administrative transfer to H10W 72/59, H10W 72/5524 and H10W 72/952 simultaneously>
D	H01L 2224/48716	<administrative transfer to H10W 72/59, H10W 72/5524 and H10W 72/952 simultaneously>
D	H01L 2224/48717	<administrative transfer to H10W 72/59, H10W 72/5524 and H10W 72/952 simultaneously>
D	H01L 2224/48718	<administrative transfer to H10W 72/59, H10W 72/5524 and H10W 72/952 simultaneously>
D	H01L 2224/4872	<administrative transfer to H10W 72/59, H10W 72/5524 and H10W 72/952 simultaneously>
D	H01L 2224/48723	<administrative transfer to H10W 72/59, H10W 72/5524 and H10W 72/952 simultaneously>
D	H01L 2224/48724	<administrative transfer to H10W 72/59, H10W 72/5524 and H10W 72/952 simultaneously>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/48738	<administrative transfer to H10W 72/59, H10W 72/5524 and H10W 72/952 simultaneously>
D	H01L 2224/48739	<administrative transfer to H10W 72/59, H10W 72/5524 and H10W 72/952 simultaneously>
D	H01L 2224/48744	<administrative transfer to H10W 72/59, H10W 72/5524 and H10W 72/952 simultaneously>
D	H01L 2224/48747	<administrative transfer to H10W 72/59, H10W 72/5524 and H10W 72/952 simultaneously>
D	H01L 2224/48749	<administrative transfer to H10W 72/59, H10W 72/5524 and H10W 72/952 simultaneously>
D	H01L 2224/48755	<administrative transfer to H10W 72/59, H10W 72/5524 and H10W 72/952 simultaneously>
D	H01L 2224/48757	<administrative transfer to H10W 72/59, H10W 72/5524 and H10W 72/952 simultaneously>
D	H01L 2224/4876	<administrative transfer to H10W 72/59, H10W 72/5524 and H10W 72/952 simultaneously>
D	H01L 2224/48763	<administrative transfer to H10W 72/59, H10W 72/5524 and H10W 72/952 simultaneously>
D	H01L 2224/48764	<administrative transfer to H10W 72/59, H10W 72/5524 and H10W 72/952 simultaneously>
D	H01L 2224/48766	<administrative transfer to H10W 72/59, H10W 72/5524 and H10W 72/952 simultaneously>
D	H01L 2224/48769	<administrative transfer to H10W 72/59, H10W 72/5524 and H10W 72/952 simultaneously>
D	H01L 2224/4877	<administrative transfer to H10W 72/59, H10W 72/5524 and H10W 72/952 simultaneously>
D	H01L 2224/48771	<administrative transfer to H10W 72/59, H10W 72/5524 and H10W 72/952 simultaneously>
D	H01L 2224/48772	<administrative transfer to H10W 72/59, H10W 72/5524 and H10W 72/952 simultaneously>
D	H01L 2224/48773	<administrative transfer to H10W 72/59, H10W 72/5524 and H10W 72/952 simultaneously>
D	H01L 2224/48778	<administrative transfer to H10W 72/59, H10W 72/5524 and H10W 72/952 simultaneously>
D	H01L 2224/48779	<administrative transfer to H10W 72/59, H10W 72/5524 and H10W 72/952 simultaneously>
D	H01L 2224/4878	<administrative transfer to H10W 72/59, H10W 72/5524 and H10W 72/952 simultaneously>
D	H01L 2224/48781	<administrative transfer to H10W 72/59, H10W 72/5524 and H10W 72/952 simultaneously>
D	H01L 2224/48783	<administrative transfer to H10W 72/59, H10W 72/5524 and H10W 72/952 simultaneously>
D	H01L 2224/48784	<administrative transfer to H10W 72/59, H10W 72/5524 and H10W 72/952 simultaneously>
D	H01L 2224/48786	<administrative transfer to H10W 72/59, H10W 72/5524 and H10W 72/953 simultaneously>
D	H01L 2224/48787	<administrative transfer to H10W 72/59, H10W 72/5524 and H10W 72/953 simultaneously>
D	H01L 2224/48788	<administrative transfer to H10W 72/59, H10W 72/5524 and H10W 72/953 simultaneously>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/4879	<administrative transfer to H10W 72/59, H10W 72/5524 and H10W 72/953 simultaneously>
D	H01L 2224/48791	<administrative transfer to H10W 72/59, H10W 72/5524 and H10W 72/953 simultaneously>
D	H01L 2224/48793	<administrative transfer to H10W 72/59, H10W 72/5524 and H10W 72/953 simultaneously>
D	H01L 2224/48794	<administrative transfer to H10W 72/59, H10W 72/5524 and H10W 72/953 simultaneously>
D	H01L 2224/48798	<administrative transfer to H10W 72/59, H10W 72/5524 and H10W 72/953 simultaneously>
D	H01L 2224/48799	<administrative transfer to H10W 72/59 and H10W 72/5525 simultaneously>
D	H01L 2224/488	<administrative transfer to H10W 72/59, H10W 72/5525 and H10W 72/952 simultaneously>
D	H01L 2224/48801	<administrative transfer to H10W 72/59, H10W 72/5525 and H10W 72/952 simultaneously>
D	H01L 2224/48805	<administrative transfer to H10W 72/59, H10W 72/5525 and H10W 72/952 simultaneously>
D	H01L 2224/48809	<administrative transfer to H10W 72/59, H10W 72/5525 and H10W 72/952 simultaneously>
D	H01L 2224/48811	<administrative transfer to H10W 72/59, H10W 72/5525 and H10W 72/952 simultaneously>
D	H01L 2224/48813	<administrative transfer to H10W 72/59, H10W 72/5525 and H10W 72/952 simultaneously>
D	H01L 2224/48814	<administrative transfer to H10W 72/59, H10W 72/5525 and H10W 72/952 simultaneously>
D	H01L 2224/48816	<administrative transfer to H10W 72/59, H10W 72/5525 and H10W 72/952 simultaneously>
D	H01L 2224/48817	<administrative transfer to H10W 72/59, H10W 72/5525 and H10W 72/952 simultaneously>
D	H01L 2224/48818	<administrative transfer to H10W 72/59, H10W 72/5525 and H10W 72/952 simultaneously>
D	H01L 2224/4882	<administrative transfer to H10W 72/59, H10W 72/5525 and H10W 72/952 simultaneously>
D	H01L 2224/48823	<administrative transfer to H10W 72/59, H10W 72/5525 and H10W 72/952 simultaneously>
D	H01L 2224/48824	<administrative transfer to H10W 72/59, H10W 72/5525 and H10W 72/952 simultaneously>
D	H01L 2224/48838	<administrative transfer to H10W 72/59, H10W 72/5525 and H10W 72/952 simultaneously>
D	H01L 2224/48839	<administrative transfer to H10W 72/59, H10W 72/5525 and H10W 72/952 simultaneously>
D	H01L 2224/48844	<administrative transfer to H10W 72/59, H10W 72/5525 and H10W 72/952 simultaneously>
D	H01L 2224/48847	<administrative transfer to H10W 72/59, H10W 72/5525 and H10W 72/952 simultaneously>
D	H01L 2224/48849	<administrative transfer to H10W 72/59, H10W 72/5525 and H10W 72/952 simultaneously>
D	H01L 2224/48855	<administrative transfer to H10W 72/59, H10W 72/5525 and H10W 72/952 simultaneously>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/48857	H10W 72/59, H10W 72/5525, H10W 72/952
D	H01L 2224/4886	<administrative transfer to H10W 72/59, H10W 72/5525 and H10W 72/952 simultaneously>
D	H01L 2224/48863	<administrative transfer to H10W 72/59, H10W 72/5525 and H10W 72/952 simultaneously>
D	H01L 2224/48864	<administrative transfer to H10W 72/59, H10W 72/5525 and H10W 72/952 simultaneously>
D	H01L 2224/48866	<administrative transfer to H10W 72/59, H10W 72/5525 and H10W 72/952 simultaneously>
D	H01L 2224/48869	<administrative transfer to H10W 72/59, H10W 72/5525 and H10W 72/952 simultaneously>
D	H01L 2224/4887	<administrative transfer to H10W 72/59, H10W 72/5525 and H10W 72/952 simultaneously>
D	H01L 2224/48871	<administrative transfer to H10W 72/59, H10W 72/5525 and H10W 72/952 simultaneously>
D	H01L 2224/48872	<administrative transfer to H10W 72/59, H10W 72/5525 and H10W 72/952 simultaneously>
D	H01L 2224/48873	<administrative transfer to H10W 72/59, H10W 72/5525 and H10W 72/952 simultaneously>
D	H01L 2224/48878	<administrative transfer to H10W 72/59, H10W 72/5525 and H10W 72/952 simultaneously>
D	H01L 2224/48879	<administrative transfer to H10W 72/59, H10W 72/5525 and H10W 72/952 simultaneously>
D	H01L 2224/4888	<administrative transfer to H10W 72/59, H10W 72/5525 and H10W 72/952 simultaneously>
D	H01L 2224/48881	<administrative transfer to H10W 72/59, H10W 72/5525 and H10W 72/952 simultaneously>
D	H01L 2224/48883	<administrative transfer to H10W 72/59, H10W 72/5525 and H10W 72/952 simultaneously>
D	H01L 2224/48884	<administrative transfer to H10W 72/59, H10W 72/5525 and H10W 72/952 simultaneously>
D	H01L 2224/48886	<administrative transfer to H10W 72/59, H10W 72/5525 and H10W 72/953 simultaneously>
D	H01L 2224/48887	<administrative transfer to H10W 72/59, H10W 72/5525 and H10W 72/953 simultaneously>
D	H01L 2224/48888	<administrative transfer to H10W 72/59, H10W 72/5525 and H10W 72/953 simultaneously>
D	H01L 2224/4889	<administrative transfer to H10W 72/59, H10W 72/5525 and H10W 72/953 simultaneously>
D	H01L 2224/48891	<administrative transfer to H10W 72/59, H10W 72/5525 and H10W 72/953 simultaneously>
D	H01L 2224/48893	<administrative transfer to H10W 72/59, H10W 72/5525 and H10W 72/953 simultaneously>
D	H01L 2224/48894	<administrative transfer to H10W 72/59, H10W 72/5525 and H10W 72/953 simultaneously>
D	H01L 2224/48898	<administrative transfer to H10W 72/59, H10W 72/5525 and H10W 72/953 simultaneously>
D	H01L 2224/4899	<administrative transfer to H10W 72/581>
D	H01L 2224/48991	<administrative transfer to H10W 72/581>
D	H01L 2224/48992	<administrative transfer to H10W 72/07553>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/48993	<administrative transfer to H10W 72/585>
D	H01L 2224/48996	<administrative transfer to H10W 72/581>
D	H01L 2224/48997	<administrative transfer to H10W 72/583>
D	H01L 2224/48998	<administrative transfer to H10W 72/585>
D	H01L 2224/49	<administrative transfer to H10W 72/50>
D	H01L 2224/4901	<administrative transfer to H10W 72/07552 and H10W 72/528 simultaneously>
D	H01L 2224/4903	<administrative transfer to H10W 72/07552 and H10W 72/527 simultaneously>
D	H01L 2224/4905	<administrative transfer to H10W 72/07552 and H10W 72/537 simultaneously>
D	H01L 2224/49051	<administrative transfer to H10W 72/07553 and H10W 72/537 simultaneously>
D	H01L 2224/49052	<administrative transfer to H10W 72/07553 and H10W 72/537 simultaneously>
D	H01L 2224/4909	<administrative transfer to H10W 72/07553 and H10W 72/537 simultaneously>
D	H01L 2224/49095	<administrative transfer to H10W 72/07553 and H10W 72/537 simultaneously>
D	H01L 2224/49096	<administrative transfer to H10W 72/07553 and H10W 72/537 simultaneously>
D	H01L 2224/49097	<administrative transfer to H10W 72/07553 and H10W 72/537 simultaneously>
D	H01L 2224/491	<administrative transfer to H10W 72/07554 and H10W 72/547 simultaneously>
D	H01L 2224/49105	<administrative transfer to H10W 72/07554 and H10W 72/547 simultaneously>
D	H01L 2224/49107	<administrative transfer to H10W 72/07554 and H10W 72/547 simultaneously>
D	H01L 2224/49109	<administrative transfer to H10W 72/07554 and H10W 72/547 simultaneously>
D	H01L 2224/4911	<administrative transfer to H10W 72/5473>
D	H01L 2224/49111	<administrative transfer to H10W 72/5475>
D	H01L 2224/49112	<administrative transfer to H10W 72/5473>
D	H01L 2224/49113	<administrative transfer to H10W 72/5473>
D	H01L 2224/4912	<administrative transfer to H10W 72/07554>
D	H01L 2224/4917	<administrative transfer to H10W 72/07554>
D	H01L 2224/49171	<administrative transfer to H10W 72/5449>
D	H01L 2224/49173	<administrative transfer to H10W 72/5449>
D	H01L 2224/49174	<administrative transfer to H10W 72/07554>
D	H01L 2224/49175	<administrative transfer to H10W 72/5445>
D	H01L 2224/49176	<administrative transfer to H10W 72/5445>
D	H01L 2224/49177	<administrative transfer to H10W 72/07554>
D	H01L 2224/49179	<administrative transfer to H10W 72/07554>
D	H01L 2224/4918	<administrative transfer to H10W 72/07554>
D	H01L 2224/494	<administrative transfer to H10W 72/50>
D	H01L 2224/4941	<administrative transfer to H10W 72/547 and H10W 72/5434 simultaneously>
D	H01L 2224/4942	<administrative transfer to H10W 72/547, H10W 72/5434 and H10W 72/536 simultaneously>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/49421	<administrative transfer to H10W 72/547, H10W 72/5434 and H10W 72/536 simultaneously>
D	H01L 2224/49422	<administrative transfer to H10W 72/547, H10W 72/5434 and H10W 72/536 simultaneously>
D	H01L 2224/49425	<administrative transfer to H10W 72/547, H10W 72/5434 and H10W 72/5363 simultaneously>
D	H01L 2224/49426	<administrative transfer to H10W 72/547, H10W 72/5434 and H10W 72/5363 simultaneously>
D	H01L 2224/49427	<administrative transfer to H10W 72/547, H10W 72/5434 and H10W 72/5363 simultaneously>
D	H01L 2224/49429	<administrative transfer to H10W 72/547, H10W 72/5434, H10W 72/536 and H10W 72/5363 simultaneously>
D	H01L 2224/4943	<administrative transfer to H10W 72/547 and H10W 72/07554 simultaneously>
D	H01L 2224/49431	<administrative transfer to H10W 72/547 and H10W 72/07554 simultaneously>
D	H01L 2224/49433	<administrative transfer to H10W 72/547 and H10W 72/07554 simultaneously>
D	H01L 2224/4945	<administrative transfer to H10W 72/537 and H10W 72/07553 simultaneously>
D	H01L 2224/495	<administrative transfer to H10W 72/07555 and H10W 72/551 simultaneously>
D	H01L 2224/49505	<administrative transfer to H10W 72/07555 and H10W 72/557 simultaneously>
D	H01L 2224/50	<administrative transfer to H10W 72/701>
D	H01L 2224/63	<administrative transfer to H10W 72/00>
D	H01L 2224/64	<administrative transfer to H10W 72/00>
D	H01L 2224/65	<administrative transfer to H10W 72/00>
D	H01L 2224/66	<administrative transfer to H10W 72/00>
D	H01L 2224/67	<administrative transfer to H10W 72/00>
D	H01L 2224/68	<administrative transfer to H10W 72/00>
D	H01L 2224/69	<administrative transfer to H10W 72/00>
D	H01L 2224/70	<administrative transfer to H10W 72/00>
D	H01L 2224/71	<administrative transfer to H10W 72/00>
D	H01L 2224/72	<administrative transfer to H10W 72/00>
D	H01L 2224/73	<administrative transfer to H10W 72/851>
D	H01L 2224/731	<administrative transfer to H10W 72/851>
D	H01L 2224/73101	<administrative transfer to H10W 72/853>
D	H01L 2224/73103	<administrative transfer to H10W 72/856>
D	H01L 2224/73104	<administrative transfer to H10W 74/15>
D	H01L 2224/73151	<administrative transfer to H10W 72/874>
D	H01L 2224/73153	<administrative transfer to H10W 72/856>
D	H01L 2224/732	<administrative transfer to H10W 72/851>
D	H01L 2224/73201	<administrative transfer to H10W 72/853>
D	H01L 2224/73203	<administrative transfer to H10W 72/856>
D	H01L 2224/73204	<administrative transfer to H10W 74/15>
D	H01L 2224/73205	<administrative transfer to H10W 72/862>
D	H01L 2224/73207	<administrative transfer to H10W 72/859>
D	H01L 2224/73209	<administrative transfer to H10W 72/853>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/73211	<administrative transfer to H10W 72/853>
D	H01L 2224/73213	<administrative transfer to H10W 72/868>
D	H01L 2224/73215	<administrative transfer to H10W 72/865>
D	H01L 2224/73217	<administrative transfer to H10W 72/853>
D	H01L 2224/73219	<administrative transfer to H10W 72/853>
D	H01L 2224/73221	<administrative transfer to H10W 72/871>
D	H01L 2224/73223	<administrative transfer to H10W 72/853>
D	H01L 2224/73225	<administrative transfer to H10W 72/853>
D	H01L 2224/73227	<administrative transfer to H10W 72/853>
D	H01L 2224/73229	<administrative transfer to H10W 72/853>
D	H01L 2224/73231	<administrative transfer to H10W 72/853>
D	H01L 2224/73251	<administrative transfer to H10W 72/874>
D	H01L 2224/73253	<administrative transfer to H10W 72/877>
D	H01L 2224/73255	<administrative transfer to H10W 72/881>
D	H01L 2224/73257	<administrative transfer to H10W 72/879>
D	H01L 2224/73259	<administrative transfer to H10W 72/874>
D	H01L 2224/73261	<administrative transfer to H10W 72/874>
D	H01L 2224/73263	<administrative transfer to H10W 72/886>
D	H01L 2224/73265	<administrative transfer to H10W 72/884>
D	H01L 2224/73267	<administrative transfer to H10W 72/874>
D	H01L 2224/73269	<administrative transfer to H10W 72/874>
D	H01L 2224/73271	<administrative transfer to H10W 72/889>
D	H01L 2224/73273	<administrative transfer to H10W 72/874>
D	H01L 2224/73275	<administrative transfer to H10W 72/874>
D	H01L 2224/73277	<administrative transfer to H10W 72/874>
D	H01L 2224/73279	<administrative transfer to H10W 72/874>
D	H01L 2224/73281	<administrative transfer to H10W 72/874>
D	H01L 2224/74	<administrative transfer to H10W 72/071>
D	H01L 2224/741	<administrative transfer to H10W 72/011>
D	H01L 2224/742	<administrative transfer to H10W 72/0112>
D	H01L 2224/743	<administrative transfer to H10W 72/0113>
D	H01L 2224/744	<administrative transfer to H10W 72/0115>
D	H01L 2224/745	<administrative transfer to H10W 72/0116>
D	H01L 2224/749	<administrative transfer to H10W 72/011>
D	H01L 2224/75	<administrative transfer to H10W 72/0711>
D	H01L 2224/75001	<administrative transfer to H10W 72/07113>
D	H01L 2224/7501	<administrative transfer to H10W 72/07118>
D	H01L 2224/751	<administrative transfer to H10W 72/07125>
D	H01L 2224/75101	<administrative transfer to H10W 72/07125>
D	H01L 2224/75102	<administrative transfer to H10W 72/07125>
D	H01L 2224/7511	<administrative transfer to H10W 72/07125>
D	H01L 2224/7515	<administrative transfer to H10W 72/07131>
D	H01L 2224/75151	<administrative transfer to H10W 72/07131>
D	H01L 2224/75152	<administrative transfer to H10W 72/07131>
D	H01L 2224/75153	<administrative transfer to H10W 72/07131>
D	H01L 2224/75155	<administrative transfer to H10W 72/07131>
D	H01L 2224/75158	<administrative transfer to H10W 72/07131>
D	H01L 2224/75161	<administrative transfer to H10W 72/07131>
D	H01L 2224/7517	<administrative transfer to H10W 72/07131>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/75171	<administrative transfer to H10W 72/07131>
D	H01L 2224/7518	<administrative transfer to H10W 72/07131>
D	H01L 2224/75181	<administrative transfer to H10W 72/07131>
D	H01L 2224/75182	<administrative transfer to H10W 72/07131>
D	H01L 2224/75183	<administrative transfer to H10W 72/07131>
D	H01L 2224/75184	<administrative transfer to H10W 72/07131>
D	H01L 2224/75185	<administrative transfer to H10W 72/07131>
D	H01L 2224/75186	<administrative transfer to H10W 72/07131>
D	H01L 2224/75187	<administrative transfer to H10W 72/07131>
D	H01L 2224/75188	<administrative transfer to H10W 72/07131>
D	H01L 2224/75189	<administrative transfer to H10W 72/07131>
D	H01L 2224/752	<administrative transfer to H10W 72/07139>
D	H01L 2224/7525	<administrative transfer to H10W 72/07141>
D	H01L 2224/75251	<administrative transfer to H10W 72/07141>
D	H01L 2224/75252	<administrative transfer to H10W 72/07141>
D	H01L 2224/75253	<administrative transfer to H10W 72/07141>
D	H01L 2224/7526	<administrative transfer to H10W 72/07141>
D	H01L 2224/75261	<administrative transfer to H10W 72/07141>
D	H01L 2224/75262	<administrative transfer to H10W 72/07141>
D	H01L 2224/75263	<administrative transfer to H10W 72/07141>
D	H01L 2224/75264	<administrative transfer to H10W 72/07141>
D	H01L 2224/75265	<administrative transfer to H10W 72/07141>
D	H01L 2224/75266	<administrative transfer to H10W 72/07141>
D	H01L 2224/75267	<administrative transfer to H10W 72/07141>
D	H01L 2224/75268	<administrative transfer to H10W 72/07141>
D	H01L 2224/75269	<administrative transfer to H10W 72/07141>
D	H01L 2224/7527	<administrative transfer to H10W 72/07141>
D	H01L 2224/75271	<administrative transfer to H10W 72/07141>
D	H01L 2224/75272	<administrative transfer to H10W 72/07141>
D	H01L 2224/7528	<administrative transfer to H10W 72/07141>
D	H01L 2224/75281	<administrative transfer to H10W 72/07141>
D	H01L 2224/75282	<administrative transfer to H10W 72/07141>
D	H01L 2224/75283	<administrative transfer to H10W 72/07141>
D	H01L 2224/753	<administrative transfer to H10W 72/07141>
D	H01L 2224/75301	<administrative transfer to H10W 72/07141>
D	H01L 2224/75302	<administrative transfer to H10W 72/07141>
D	H01L 2224/75303	<administrative transfer to H10W 72/07141>
D	H01L 2224/75304	<administrative transfer to H10W 72/07141>
D	H01L 2224/75305	<administrative transfer to H10W 72/07141>
D	H01L 2224/7531	<administrative transfer to H10W 72/07141>
D	H01L 2224/75312	<administrative transfer to H10W 72/07141>
D	H01L 2224/75313	<administrative transfer to H10W 72/07141>
D	H01L 2224/75314	<administrative transfer to H10W 72/07141>
D	H01L 2224/75315	<administrative transfer to H10W 72/07141>
D	H01L 2224/75316	<administrative transfer to H10W 72/07141>
D	H01L 2224/75317	<administrative transfer to H10W 72/07141>
D	H01L 2224/75318	<administrative transfer to H10W 72/07141>
D	H01L 2224/7532	<administrative transfer to H10W 72/07141>
D	H01L 2224/75343	<administrative transfer to H10W 72/07141>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/75344	<administrative transfer to H10W 72/07141>
D	H01L 2224/75345	<administrative transfer to H10W 72/07141>
D	H01L 2224/75346	<administrative transfer to H10W 72/07141>
D	H01L 2224/75347	<administrative transfer to H10W 72/07141>
D	H01L 2224/75348	<administrative transfer to H10W 72/07141>
D	H01L 2224/75349	<administrative transfer to H10W 72/07141>
D	H01L 2224/7535	<administrative transfer to H10W 72/07141>
D	H01L 2224/75351	<administrative transfer to H10W 72/07141>
D	H01L 2224/75352	<administrative transfer to H10W 72/07141>
D	H01L 2224/75353	<administrative transfer to H10W 72/07141>
D	H01L 2224/75354	<administrative transfer to H10W 72/07141>
D	H01L 2224/75355	<administrative transfer to H10W 72/07141>
D	H01L 2224/755	<administrative transfer to H10W 72/07152>
D	H01L 2224/75501	<administrative transfer to H10W 72/07152>
D	H01L 2224/75502	<administrative transfer to H10W 72/07152>
D	H01L 2224/7555	<administrative transfer to H10W 72/07163>
D	H01L 2224/756	<administrative transfer to H10W 72/07168>
D	H01L 2224/75601	<administrative transfer to H10W 72/07168>
D	H01L 2224/75611	<administrative transfer to H10W 72/07168>
D	H01L 2224/75621	<administrative transfer to H10W 72/07168>
D	H01L 2224/7565	<administrative transfer to H10W 72/07173>
D	H01L 2224/75651	<administrative transfer to H10W 72/07173>
D	H01L 2224/75652	<administrative transfer to H10W 72/07173>
D	H01L 2224/75653	<administrative transfer to H10W 72/07173>
D	H01L 2224/75654	<administrative transfer to H10W 72/07173>
D	H01L 2224/75655	<administrative transfer to H10W 72/07173>
D	H01L 2224/757	<administrative transfer to H10W 72/07178>
D	H01L 2224/75701	<administrative transfer to H10W 72/07178>
D	H01L 2224/75702	<administrative transfer to H10W 72/07178>
D	H01L 2224/75703	<administrative transfer to H10W 72/07178>
D	H01L 2224/75704	<administrative transfer to H10W 72/07178>
D	H01L 2224/75705	<administrative transfer to H10W 72/07178>
D	H01L 2224/75723	<administrative transfer to H10W 72/07178>
D	H01L 2224/75724	<administrative transfer to H10W 72/07178>
D	H01L 2224/75725	<administrative transfer to H10W 72/07178>
D	H01L 2224/75733	<administrative transfer to H10W 72/07178>
D	H01L 2224/75734	<administrative transfer to H10W 72/07178>
D	H01L 2224/75735	<administrative transfer to H10W 72/07178>
D	H01L 2224/75743	<administrative transfer to H10W 72/07178>
D	H01L 2224/75744	<administrative transfer to H10W 72/07178>
D	H01L 2224/75745	<administrative transfer to H10W 72/07178>
D	H01L 2224/75753	<administrative transfer to H10W 72/07178>
D	H01L 2224/75754	<administrative transfer to H10W 72/07178>
D	H01L 2224/75755	<administrative transfer to H10W 72/07178>
D	H01L 2224/75756	<administrative transfer to H10W 72/07178>
D	H01L 2224/758	<administrative transfer to H10W 72/07173>
D	H01L 2224/75801	<administrative transfer to H10W 72/07173>
D	H01L 2224/75802	<administrative transfer to H10W 72/07173>
D	H01L 2224/75803	<administrative transfer to H10W 72/07173>

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D	H01L 2224/75804	<administrative transfer to H10W 72/07173>
D	H01L 2224/75821	<administrative transfer to H10W 72/07173>
D	H01L 2224/75822	<administrative transfer to H10W 72/07173>
D	H01L 2224/75823	<administrative transfer to H10W 72/07173>
D	H01L 2224/75824	<administrative transfer to H10W 72/07173>
D	H01L 2224/75841	<administrative transfer to H10W 72/07173>
D	H01L 2224/75842	<administrative transfer to H10W 72/07173>
D	H01L 2224/75843	<administrative transfer to H10W 72/07173>
D	H01L 2224/759	<administrative transfer to H10W 72/07183>
D	H01L 2224/75901	<administrative transfer to H10W 72/07183>
D	H01L 2224/7592	<administrative transfer to H10W 72/07183>
D	H01L 2224/75925	<administrative transfer to H10W 72/07183>
D	H01L 2224/7595	<administrative transfer to H10W 72/07131>
D	H01L 2224/7598	<administrative transfer to H10W 72/0711>
D	H01L 2224/75981	<administrative transfer to H10W 72/07188>
D	H01L 2224/75982	<administrative transfer to H10W 72/07188>
D	H01L 2224/75983	<administrative transfer to H10W 72/07188>
D	H01L 2224/75984	<administrative transfer to H10W 72/07188>
D	H01L 2224/75985	<administrative transfer to H10W 72/07188>
D	H01L 2224/75986	<administrative transfer to H10W 72/07188>
D	H01L 2224/75987	<administrative transfer to H10W 72/07188>
D	H01L 2224/75988	<administrative transfer to H10W 72/07188>
D	H01L 2224/76	<administrative transfer to H10W 72/07188>
D	H01L 2224/76001	<administrative transfer to H10W 72/0711>
D	H01L 2224/7601	<administrative transfer to H10W 72/07118>
D	H01L 2224/761	<administrative transfer to H10W 72/07125>
D	H01L 2224/76101	<administrative transfer to H10W 72/07125>
D	H01L 2224/76102	<administrative transfer to H10W 72/07125>
D	H01L 2224/7611	<administrative transfer to H10W 72/07125>
D	H01L 2224/7615	<administrative transfer to H10W 72/07131>
D	H01L 2224/76151	<administrative transfer to H10W 72/07131>
D	H01L 2224/76152	<administrative transfer to H10W 72/07131>
D	H01L 2224/76155	<administrative transfer to H10W 72/07131>
D	H01L 2224/76158	<administrative transfer to H10W 72/07131>
D	H01L 2224/76161	<administrative transfer to H10W 72/07131>
D	H01L 2224/7617	<administrative transfer to H10W 72/07131>
D	H01L 2224/76171	<administrative transfer to H10W 72/07131>
D	H01L 2224/7618	<administrative transfer to H10W 72/07131>
D	H01L 2224/76181	<administrative transfer to H10W 72/07131>
D	H01L 2224/76182	<administrative transfer to H10W 72/07131>
D	H01L 2224/76183	<administrative transfer to H10W 72/07131>
D	H01L 2224/76184	<administrative transfer to H10W 72/07131>
D	H01L 2224/76185	<administrative transfer to H10W 72/07131>
D	H01L 2224/76186	<administrative transfer to H10W 72/07131>
D	H01L 2224/76187	<administrative transfer to H10W 72/07131>
D	H01L 2224/76188	<administrative transfer to H10W 72/07131>
D	H01L 2224/76189	<administrative transfer to H10W 72/07131>
D	H01L 2224/762	<administrative transfer to H10W 72/07139>
D	H01L 2224/7625	<administrative transfer to H10W 72/07141>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/76251	<administrative transfer to H10W 72/07141>
D	H01L 2224/76252	<administrative transfer to H10W 72/07141>
D	H01L 2224/76253	<administrative transfer to H10W 72/07141>
D	H01L 2224/7626	<administrative transfer to H10W 72/07141>
D	H01L 2224/76261	<administrative transfer to H10W 72/07141>
D	H01L 2224/76262	<administrative transfer to H10W 72/07141>
D	H01L 2224/76263	<administrative transfer to H10W 72/07141>
D	H01L 2224/76264	<administrative transfer to H10W 72/07141>
D	H01L 2224/76265	<administrative transfer to H10W 72/07141>
D	H01L 2224/76266	<administrative transfer to H10W 72/07141>
D	H01L 2224/76267	<administrative transfer to H10W 72/07141>
D	H01L 2224/76268	<administrative transfer to H10W 72/07141>
D	H01L 2224/76269	<administrative transfer to H10W 72/07141>
D	H01L 2224/7627	<administrative transfer to H10W 72/07141>
D	H01L 2224/76271	<administrative transfer to H10W 72/07141>
D	H01L 2224/76272	<administrative transfer to H10W 72/07141>
D	H01L 2224/7628	<administrative transfer to H10W 72/07141>
D	H01L 2224/76281	<administrative transfer to H10W 72/07141>
D	H01L 2224/76282	<administrative transfer to H10W 72/07141>
D	H01L 2224/76283	<administrative transfer to H10W 72/07141>
D	H01L 2224/763	<administrative transfer to H10W 72/07141>
D	H01L 2224/76301	<administrative transfer to H10W 72/07141>
D	H01L 2224/76302	<administrative transfer to H10W 72/07141>
D	H01L 2224/76303	<administrative transfer to H10W 72/07141>
D	H01L 2224/76304	<administrative transfer to H10W 72/07141>
D	H01L 2224/76305	<administrative transfer to H10W 72/07141>
D	H01L 2224/7631	<administrative transfer to H10W 72/07141>
D	H01L 2224/76312	<administrative transfer to H10W 72/07141>
D	H01L 2224/76313	<administrative transfer to H10W 72/07141>
D	H01L 2224/76314	<administrative transfer to H10W 72/07141>
D	H01L 2224/76315	<administrative transfer to H10W 72/07141>
D	H01L 2224/76316	<administrative transfer to H10W 72/07141>
D	H01L 2224/76317	<administrative transfer to H10W 72/07141>
D	H01L 2224/76318	<administrative transfer to H10W 72/07141>
D	H01L 2224/7632	<administrative transfer to H10W 72/07141>
D	H01L 2224/76343	<administrative transfer to H10W 72/07141>
D	H01L 2224/76344	<administrative transfer to H10W 72/07141>
D	H01L 2224/76345	<administrative transfer to H10W 72/07141>
D	H01L 2224/76346	<administrative transfer to H10W 72/07141>
D	H01L 2224/76347	<administrative transfer to H10W 72/07141>
D	H01L 2224/76348	<administrative transfer to H10W 72/07141>
D	H01L 2224/76349	<administrative transfer to H10W 72/07141>
D	H01L 2224/7635	<administrative transfer to H10W 72/07141>
D	H01L 2224/76351	<administrative transfer to H10W 72/07141>
D	H01L 2224/76352	<administrative transfer to H10W 72/07141>
D	H01L 2224/76353	<administrative transfer to H10W 72/07141>
D	H01L 2224/76354	<administrative transfer to H10W 72/07141>
D	H01L 2224/76355	<administrative transfer to H10W 72/07141>
D	H01L 2224/765	<administrative transfer to H10W 72/07152>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/76501	<administrative transfer to H10W 72/07152>
D	H01L 2224/76502	<administrative transfer to H10W 72/07152>
D	H01L 2224/7655	<administrative transfer to H10W 72/07163>
D	H01L 2224/76552	<administrative transfer to H10W 72/07163>
D	H01L 2224/76554	<administrative transfer to H10W 72/07163>
D	H01L 2224/766	<administrative transfer to H10W 72/07168>
D	H01L 2224/76601	<administrative transfer to H10W 72/07168>
D	H01L 2224/76611	<administrative transfer to H10W 72/07168>
D	H01L 2224/76621	<administrative transfer to H10W 72/07168>
D	H01L 2224/7665	<administrative transfer to H10W 72/07173>
D	H01L 2224/76651	<administrative transfer to H10W 72/07173>
D	H01L 2224/76652	<administrative transfer to H10W 72/07173>
D	H01L 2224/76653	<administrative transfer to H10W 72/07173>
D	H01L 2224/76654	<administrative transfer to H10W 72/07173>
D	H01L 2224/76655	<administrative transfer to H10W 72/07173>
D	H01L 2224/767	<administrative transfer to H10W 72/07178>
D	H01L 2224/76701	<administrative transfer to H10W 72/07178>
D	H01L 2224/76702	<administrative transfer to H10W 72/07178>
D	H01L 2224/76703	<administrative transfer to H10W 72/07178>
D	H01L 2224/76704	<administrative transfer to H10W 72/07178>
D	H01L 2224/76705	<administrative transfer to H10W 72/07178>
D	H01L 2224/76723	<administrative transfer to H10W 72/07178>
D	H01L 2224/76724	<administrative transfer to H10W 72/07178>
D	H01L 2224/76725	<administrative transfer to H10W 72/07178>
D	H01L 2224/76733	<administrative transfer to H10W 72/07178>
D	H01L 2224/76734	<administrative transfer to H10W 72/07178>
D	H01L 2224/76735	<administrative transfer to H10W 72/07178>
D	H01L 2224/76743	<administrative transfer to H10W 72/07178>
D	H01L 2224/76744	<administrative transfer to H10W 72/07178>
D	H01L 2224/76745	<administrative transfer to H10W 72/07178>
D	H01L 2224/76753	<administrative transfer to H10W 72/07178>
D	H01L 2224/76754	<administrative transfer to H10W 72/07178>
D	H01L 2224/76755	<administrative transfer to H10W 72/07178>
D	H01L 2224/76756	<administrative transfer to H10W 72/07178>
D	H01L 2224/768	<administrative transfer to H10W 72/07173>
D	H01L 2224/76801	<administrative transfer to H10W 72/07173>
D	H01L 2224/76802	<administrative transfer to H10W 72/07173>
D	H01L 2224/76803	<administrative transfer to H10W 72/07173>
D	H01L 2224/76804	<administrative transfer to H10W 72/07173>
D	H01L 2224/76821	<administrative transfer to H10W 72/07173>
D	H01L 2224/76822	<administrative transfer to H10W 72/07173>
D	H01L 2224/76823	<administrative transfer to H10W 72/07173>
D	H01L 2224/76824	<administrative transfer to H10W 72/07173>
D	H01L 2224/76841	<administrative transfer to H10W 72/07173>
D	H01L 2224/76842	<administrative transfer to H10W 72/07173>
D	H01L 2224/76843	<administrative transfer to H10W 72/07173>
D	H01L 2224/769	<administrative transfer to H10W 72/07183>
D	H01L 2224/76901	<administrative transfer to H10W 72/07183>
D	H01L 2224/7692	<administrative transfer to H10W 72/07183>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/76925	<administrative transfer to H10W 72/07183>
D	H01L 2224/7695	<administrative transfer to H10W 72/07131>
D	H01L 2224/7698	<administrative transfer to H10W 72/0711>
D	H01L 2224/76981	<administrative transfer to H10W 72/07188>
D	H01L 2224/76982	<administrative transfer to H10W 72/07188>
D	H01L 2224/76983	<administrative transfer to H10W 72/07188>
D	H01L 2224/76984	<administrative transfer to H10W 72/07188>
D	H01L 2224/76985	<administrative transfer to H10W 72/07188>
D	H01L 2224/76986	<administrative transfer to H10W 72/07188>
D	H01L 2224/76987	<administrative transfer to H10W 72/07188>
D	H01L 2224/76988	<administrative transfer to H10W 72/07188>
D	H01L 2224/77	<administrative transfer to H10W 72/0711>
D	H01L 2224/77001	<administrative transfer to H10W 72/07113>
D	H01L 2224/7701	<administrative transfer to H10W 72/07118>
D	H01L 2224/771	<administrative transfer to H10W 72/07125>
D	H01L 2224/77101	<administrative transfer to H10W 72/07125>
D	H01L 2224/77102	<administrative transfer to H10W 72/07125>
D	H01L 2224/7711	<administrative transfer to H10W 72/07125>
D	H01L 2224/7715	<administrative transfer to H10W 72/07131>
D	H01L 2224/77151	<administrative transfer to H10W 72/07131>
D	H01L 2224/77152	<administrative transfer to H10W 72/07131>
D	H01L 2224/77153	<administrative transfer to H10W 72/07131>
D	H01L 2224/77155	<administrative transfer to H10W 72/07131>
D	H01L 2224/77158	<administrative transfer to H10W 72/07131>
D	H01L 2224/77161	<administrative transfer to H10W 72/07131>
D	H01L 2224/7717	<administrative transfer to H10W 72/07131>
D	H01L 2224/77171	<administrative transfer to H10W 72/07131>
D	H01L 2224/7718	<administrative transfer to H10W 72/07131>
D	H01L 2224/77181	<administrative transfer to H10W 72/07131>
D	H01L 2224/77182	<administrative transfer to H10W 72/07131>
D	H01L 2224/77183	<administrative transfer to H10W 72/07131>
D	H01L 2224/77184	<administrative transfer to H10W 72/07131>
D	H01L 2224/77185	<administrative transfer to H10W 72/07131>
D	H01L 2224/77186	<administrative transfer to H10W 72/07131>
D	H01L 2224/77187	<administrative transfer to H10W 72/07131>
D	H01L 2224/77188	<administrative transfer to H10W 72/07131>
D	H01L 2224/77189	<administrative transfer to H10W 72/07131>
D	H01L 2224/772	<administrative transfer to H10W 72/07139>
D	H01L 2224/7725	<administrative transfer to H10W 72/07141>
D	H01L 2224/77251	<administrative transfer to H10W 72/07141>
D	H01L 2224/77252	<administrative transfer to H10W 72/07141>
D	H01L 2224/77253	<administrative transfer to H10W 72/07141>
D	H01L 2224/7726	<administrative transfer to H10W 72/07141>
D	H01L 2224/77261	<administrative transfer to H10W 72/07141>
D	H01L 2224/77262	<administrative transfer to H10W 72/07141>
D	H01L 2224/77263	<administrative transfer to H10W 72/07141>
D	H01L 2224/77264	<administrative transfer to H10W 72/07141>
D	H01L 2224/77265	<administrative transfer to H10W 72/07141>
D	H01L 2224/77266	<administrative transfer to H10W 72/07141>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/77267	<administrative transfer to H10W 72/07141>
D	H01L 2224/77268	<administrative transfer to H10W 72/07141>
D	H01L 2224/77269	<administrative transfer to H10W 72/07141>
D	H01L 2224/7727	<administrative transfer to H10W 72/07141>
D	H01L 2224/77271	<administrative transfer to H10W 72/07141>
D	H01L 2224/77272	<administrative transfer to H10W 72/07141>
D	H01L 2224/7728	<administrative transfer to H10W 72/07141>
D	H01L 2224/77281	<administrative transfer to H10W 72/07141>
D	H01L 2224/77282	<administrative transfer to H10W 72/07141>
D	H01L 2224/77283	<administrative transfer to H10W 72/07141>
D	H01L 2224/773	<administrative transfer to H10W 72/07141>
D	H01L 2224/77313	<administrative transfer to H10W 72/07141>
D	H01L 2224/77314	<administrative transfer to H10W 72/07141>
D	H01L 2224/77315	<administrative transfer to H10W 72/07141>
D	H01L 2224/77316	<administrative transfer to H10W 72/07141>
D	H01L 2224/77317	<administrative transfer to H10W 72/07141>
D	H01L 2224/77318	<administrative transfer to H10W 72/07141>
D	H01L 2224/77319	<administrative transfer to H10W 72/07141>
D	H01L 2224/7732	<administrative transfer to H10W 72/07141>
D	H01L 2224/77321	<administrative transfer to H10W 72/07141>
D	H01L 2224/77325	<administrative transfer to H10W 72/07141>
D	H01L 2224/77326	<administrative transfer to H10W 72/07141>
D	H01L 2224/77327	<administrative transfer to H10W 72/07141>
D	H01L 2224/77328	<administrative transfer to H10W 72/07141>
D	H01L 2224/77343	<administrative transfer to H10W 72/07141>
D	H01L 2224/77344	<administrative transfer to H10W 72/07141>
D	H01L 2224/77345	<administrative transfer to H10W 72/07141>
D	H01L 2224/77346	<administrative transfer to H10W 72/07141>
D	H01L 2224/77347	<administrative transfer to H10W 72/07141>
D	H01L 2224/77348	<administrative transfer to H10W 72/07141>
D	H01L 2224/77349	<administrative transfer to H10W 72/07141>
D	H01L 2224/7735	<administrative transfer to H10W 72/07141>
D	H01L 2224/77351	<administrative transfer to H10W 72/07141>
D	H01L 2224/77352	<administrative transfer to H10W 72/07141>
D	H01L 2224/77353	<administrative transfer to H10W 72/07141>
D	H01L 2224/77354	<administrative transfer to H10W 72/07141>
D	H01L 2224/77355	<administrative transfer to H10W 72/07141>
D	H01L 2224/775	<administrative transfer to H10W 72/07152>
D	H01L 2224/77501	<administrative transfer to H10W 72/07152>
D	H01L 2224/77502	<administrative transfer to H10W 72/07152>
D	H01L 2224/7755	<administrative transfer to H10W 72/07163>
D	H01L 2224/776	<administrative transfer to H10W 72/07168>
D	H01L 2224/77601	<administrative transfer to H10W 72/07168>
D	H01L 2224/77611	<administrative transfer to H10W 72/07168>
D	H01L 2224/77621	<administrative transfer to H10W 72/07168>
D	H01L 2224/77631	<administrative transfer to H10W 72/07168>
D	H01L 2224/7765	<administrative transfer to H10W 72/07173>
D	H01L 2224/77651	<administrative transfer to H10W 72/07173>
D	H01L 2224/77652	<administrative transfer to H10W 72/07173>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/77653	<administrative transfer to H10W 72/07173>
D	H01L 2224/77654	<administrative transfer to H10W 72/07173>
D	H01L 2224/77655	<administrative transfer to H10W 72/07173>
D	H01L 2224/777	<administrative transfer to H10W 72/07178>
D	H01L 2224/77701	<administrative transfer to H10W 72/07178>
D	H01L 2224/77702	<administrative transfer to H10W 72/07178>
D	H01L 2224/77703	<administrative transfer to H10W 72/07178>
D	H01L 2224/77704	<administrative transfer to H10W 72/07178>
D	H01L 2224/77705	<administrative transfer to H10W 72/07178>
D	H01L 2224/77723	<administrative transfer to H10W 72/07178>
D	H01L 2224/77724	<administrative transfer to H10W 72/07178>
D	H01L 2224/77725	<administrative transfer to H10W 72/07178>
D	H01L 2224/77733	<administrative transfer to H10W 72/07178>
D	H01L 2224/77734	<administrative transfer to H10W 72/07178>
D	H01L 2224/77735	<administrative transfer to H10W 72/07178>
D	H01L 2224/77743	<administrative transfer to H10W 72/07178>
D	H01L 2224/77744	<administrative transfer to H10W 72/07178>
D	H01L 2224/77745	<administrative transfer to H10W 72/07178>
D	H01L 2224/77753	<administrative transfer to H10W 72/07178>
D	H01L 2224/77754	<administrative transfer to H10W 72/07178>
D	H01L 2224/77755	<administrative transfer to H10W 72/07178>
D	H01L 2224/77756	<administrative transfer to H10W 72/07178>
D	H01L 2224/778	<administrative transfer to H10W 72/07173>
D	H01L 2224/77801	<administrative transfer to H10W 72/07173>
D	H01L 2224/77802	<administrative transfer to H10W 72/07173>
D	H01L 2224/77803	<administrative transfer to H10W 72/07173>
D	H01L 2224/77804	<administrative transfer to H10W 72/07173>
D	H01L 2224/77821	<administrative transfer to H10W 72/07173>
D	H01L 2224/77822	<administrative transfer to H10W 72/07173>
D	H01L 2224/77823	<administrative transfer to H10W 72/07173>
D	H01L 2224/77824	<administrative transfer to H10W 72/07173>
D	H01L 2224/77841	<administrative transfer to H10W 72/07173>
D	H01L 2224/77842	<administrative transfer to H10W 72/07173>
D	H01L 2224/77843	<administrative transfer to H10W 72/07173>
D	H01L 2224/779	<administrative transfer to H10W 72/07183>
D	H01L 2224/77901	<administrative transfer to H10W 72/07183>
D	H01L 2224/7792	<administrative transfer to H10W 72/07183>
D	H01L 2224/77925	<administrative transfer to H10W 72/07183>
D	H01L 2224/7795	<administrative transfer to H10W 72/07131>
D	H01L 2224/7798	<administrative transfer to H10W 72/0711>
D	H01L 2224/77981	<administrative transfer to H10W 72/07188>
D	H01L 2224/77982	<administrative transfer to H10W 72/07188>
D	H01L 2224/77983	<administrative transfer to H10W 72/07188>
D	H01L 2224/77984	<administrative transfer to H10W 72/07188>
D	H01L 2224/77985	<administrative transfer to H10W 72/07188>
D	H01L 2224/77986	<administrative transfer to H10W 72/07188>
D	H01L 2224/77987	<administrative transfer to H10W 72/07188>
D	H01L 2224/77988	<administrative transfer to H10W 72/07188>
D	H01L 2224/78	<administrative transfer to H10W 72/0711>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/78001	<administrative transfer to H10W 72/07113>
D	H01L 2224/7801	<administrative transfer to H10W 72/07118>
D	H01L 2224/781	<administrative transfer to H10W 72/07125>
D	H01L 2224/78101	<administrative transfer to H10W 72/07125>
D	H01L 2224/78102	<administrative transfer to H10W 72/07125>
D	H01L 2224/7811	<administrative transfer to H10W 72/07125>
D	H01L 2224/7815	<administrative transfer to H10W 72/07131>
D	H01L 2224/782	<administrative transfer to H10W 72/07139>
D	H01L 2224/7825	<administrative transfer to H10W 72/07141>
D	H01L 2224/78251	<administrative transfer to H10W 72/07141>
D	H01L 2224/78252	<administrative transfer to H10W 72/07141>
D	H01L 2224/78253	<administrative transfer to H10W 72/07141>
D	H01L 2224/7826	<administrative transfer to H10W 72/07141>
D	H01L 2224/78261	<administrative transfer to H10W 72/07141>
D	H01L 2224/78262	<administrative transfer to H10W 72/07141>
D	H01L 2224/78263	<administrative transfer to H10W 72/07141>
D	H01L 2224/78264	<administrative transfer to H10W 72/07141>
D	H01L 2224/78265	<administrative transfer to H10W 72/07141>
D	H01L 2224/78266	<administrative transfer to H10W 72/07141>
D	H01L 2224/78267	<administrative transfer to H10W 72/07141>
D	H01L 2224/78268	<administrative transfer to H10W 72/07141>
D	H01L 2224/78269	<administrative transfer to H10W 72/07141>
D	H01L 2224/7827	<administrative transfer to H10W 72/07141>
D	H01L 2224/78271	<administrative transfer to H10W 72/07141>
D	H01L 2224/78272	<administrative transfer to H10W 72/07141>
D	H01L 2224/7828	<administrative transfer to H10W 72/07141>
D	H01L 2224/78281	<administrative transfer to H10W 72/07141>
D	H01L 2224/78282	<administrative transfer to H10W 72/07141>
D	H01L 2224/78283	<administrative transfer to H10W 72/07141>
D	H01L 2224/783	<administrative transfer to H10W 72/07141>
D	H01L 2224/78301	<administrative transfer to H10W 72/07141>
D	H01L 2224/78302	<administrative transfer to H10W 72/07141>
D	H01L 2224/78303	<administrative transfer to H10W 72/07141>
D	H01L 2224/78304	<administrative transfer to H10W 72/07141>
D	H01L 2224/78305	<administrative transfer to H10W 72/07141>
D	H01L 2224/78306	<administrative transfer to H10W 72/07141>
D	H01L 2224/78307	<administrative transfer to H10W 72/07141>
D	H01L 2224/78308	<administrative transfer to H10W 72/07141>
D	H01L 2224/78309	<administrative transfer to H10W 72/07141>
D	H01L 2224/7831	<administrative transfer to H10W 72/07141>
D	H01L 2224/78311	<administrative transfer to H10W 72/07141>
D	H01L 2224/78312	<administrative transfer to H10W 72/07141>
D	H01L 2224/78313	<administrative transfer to H10W 72/07141>
D	H01L 2224/78314	<administrative transfer to H10W 72/07141>
D	H01L 2224/78315	<administrative transfer to H10W 72/07141>
D	H01L 2224/78316	<administrative transfer to H10W 72/07141>
D	H01L 2224/78317	<administrative transfer to H10W 72/07141>
D	H01L 2224/78318	<administrative transfer to H10W 72/07141>
D	H01L 2224/78319	<administrative transfer to H10W 72/07141>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/7832	<administrative transfer to H10W 72/07141>
D	H01L 2224/78321	<administrative transfer to H10W 72/07141>
D	H01L 2224/78325	<administrative transfer to H10W 72/07141>
D	H01L 2224/78326	<administrative transfer to H10W 72/07141>
D	H01L 2224/78327	<administrative transfer to H10W 72/07141>
D	H01L 2224/78328	<administrative transfer to H10W 72/07141>
D	H01L 2224/78343	<administrative transfer to H10W 72/07141>
D	H01L 2224/78344	<administrative transfer to H10W 72/07141>
D	H01L 2224/78345	<administrative transfer to H10W 72/07141>
D	H01L 2224/78346	<administrative transfer to H10W 72/07141>
D	H01L 2224/78347	<administrative transfer to H10W 72/07141>
D	H01L 2224/78348	<administrative transfer to H10W 72/07141>
D	H01L 2224/78349	<administrative transfer to H10W 72/07141>
D	H01L 2224/7835	<administrative transfer to H10W 72/07141>
D	H01L 2224/78351	<administrative transfer to H10W 72/07141>
D	H01L 2224/78352	<administrative transfer to H10W 72/07141>
D	H01L 2224/78353	<administrative transfer to H10W 72/07141>
D	H01L 2224/78354	<administrative transfer to H10W 72/07141>
D	H01L 2224/78355	<administrative transfer to H10W 72/07141>
D	H01L 2224/785	<administrative transfer to H10W 72/07152>
D	H01L 2224/78501	<administrative transfer to H10W 72/07152>
D	H01L 2224/78502	<administrative transfer to H10W 72/07152>
D	H01L 2224/7855	<administrative transfer to H10W 72/07163>
D	H01L 2224/786	<administrative transfer to H10W 72/07168>
D	H01L 2224/78601	<administrative transfer to H10W 72/07168>
D	H01L 2224/78611	<administrative transfer to H10W 72/07168>
D	H01L 2224/78621	<administrative transfer to H10W 72/07168>
D	H01L 2224/78631	<administrative transfer to H10W 72/07168>
D	H01L 2224/7865	<administrative transfer to H10W 72/07173>
D	H01L 2224/78651	<administrative transfer to H10W 72/07173>
D	H01L 2224/78652	<administrative transfer to H10W 72/07173>
D	H01L 2224/78653	<administrative transfer to H10W 72/07173>
D	H01L 2224/78654	<administrative transfer to H10W 72/07173>
D	H01L 2224/78655	<administrative transfer to H10W 72/07173>
D	H01L 2224/787	<administrative transfer to H10W 72/07178>
D	H01L 2224/78701	<administrative transfer to H10W 72/07178>
D	H01L 2224/78702	<administrative transfer to H10W 72/07178>
D	H01L 2224/78703	<administrative transfer to H10W 72/07178>
D	H01L 2224/78704	<administrative transfer to H10W 72/07178>
D	H01L 2224/78705	<administrative transfer to H10W 72/07178>
D	H01L 2224/78723	<administrative transfer to H10W 72/07178>
D	H01L 2224/78724	<administrative transfer to H10W 72/07178>
D	H01L 2224/78725	<administrative transfer to H10W 72/07178>
D	H01L 2224/78733	<administrative transfer to H10W 72/07178>
D	H01L 2224/78734	<administrative transfer to H10W 72/07178>
D	H01L 2224/78735	<administrative transfer to H10W 72/07178>
D	H01L 2224/78743	<administrative transfer to H10W 72/07178>
D	H01L 2224/78744	<administrative transfer to H10W 72/07178>
D	H01L 2224/78745	<administrative transfer to H10W 72/07178>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/78753	<administrative transfer to H10W 72/07178>
D	H01L 2224/78754	<administrative transfer to H10W 72/07178>
D	H01L 2224/78755	<administrative transfer to H10W 72/07178>
D	H01L 2224/78756	<administrative transfer to H10W 72/07178>
D	H01L 2224/788	<administrative transfer to H10W 72/07173>
D	H01L 2224/78801	<administrative transfer to H10W 72/07173>
D	H01L 2224/78802	<administrative transfer to H10W 72/07173>
D	H01L 2224/78803	<administrative transfer to H10W 72/07173>
D	H01L 2224/78804	<administrative transfer to H10W 72/07173>
D	H01L 2224/78821	<administrative transfer to H10W 72/07173>
D	H01L 2224/78822	<administrative transfer to H10W 72/07173>
D	H01L 2224/78823	<administrative transfer to H10W 72/07173>
D	H01L 2224/78824	<administrative transfer to H10W 72/07173>
D	H01L 2224/78841	<administrative transfer to H10W 72/07173>
D	H01L 2224/78842	<administrative transfer to H10W 72/07173>
D	H01L 2224/78843	<administrative transfer to H10W 72/07173>
D	H01L 2224/789	<administrative transfer to H10W 72/07183>
D	H01L 2224/78901	<administrative transfer to H10W 72/07183>
D	H01L 2224/7892	<administrative transfer to H10W 72/07183>
D	H01L 2224/78925	<administrative transfer to H10W 72/07183>
D	H01L 2224/7895	<administrative transfer to H10W 72/07131>
D	H01L 2224/7898	<administrative transfer to H10W 72/0711>
D	H01L 2224/78981	<administrative transfer to H10W 72/07188>
D	H01L 2224/78982	<administrative transfer to H10W 72/07188>
D	H01L 2224/78983	<administrative transfer to H10W 72/07188>
D	H01L 2224/78984	<administrative transfer to H10W 72/07188>
D	H01L 2224/78985	<administrative transfer to H10W 72/07188>
D	H01L 2224/78986	<administrative transfer to H10W 72/07188>
D	H01L 2224/78987	<administrative transfer to H10W 72/07188>
D	H01L 2224/78988	<administrative transfer to H10W 72/07188>
D	H01L 2224/79	<administrative transfer to H10W 72/0711>
D	H01L 2224/79001	<administrative transfer to H10W 72/07113>
D	H01L 2224/7901	<administrative transfer to H10W 72/07118>
D	H01L 2224/791	<administrative transfer to H10W 72/07125>
D	H01L 2224/79101	<administrative transfer to H10W 72/07125>
D	H01L 2224/79102	<administrative transfer to H10W 72/07125>
D	H01L 2224/7911	<administrative transfer to H10W 72/07125>
D	H01L 2224/7915	<administrative transfer to H10W 72/07131>
D	H01L 2224/79151	<administrative transfer to H10W 72/07131>
D	H01L 2224/79152	<administrative transfer to H10W 72/07131>
D	H01L 2224/79153	<administrative transfer to H10W 72/07131>
D	H01L 2224/79155	<administrative transfer to H10W 72/07131>
D	H01L 2224/79158	<administrative transfer to H10W 72/07131>
D	H01L 2224/79161	<administrative transfer to H10W 72/07131>
D	H01L 2224/7917	<administrative transfer to H10W 72/07131>
D	H01L 2224/79171	<administrative transfer to H10W 72/07131>
D	H01L 2224/7918	<administrative transfer to H10W 72/07131>
D	H01L 2224/79181	<administrative transfer to H10W 72/07131>
D	H01L 2224/79182	<administrative transfer to H10W 72/07131>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/79183	<administrative transfer to H10W 72/07131>
D	H01L 2224/79184	<administrative transfer to H10W 72/07131>
D	H01L 2224/79185	<administrative transfer to H10W 72/07131>
D	H01L 2224/79186	<administrative transfer to H10W 72/07131>
D	H01L 2224/79187	<administrative transfer to H10W 72/07131>
D	H01L 2224/79188	<administrative transfer to H10W 72/07131>
D	H01L 2224/79189	<administrative transfer to H10W 72/07131>
D	H01L 2224/792	<administrative transfer to H10W 72/07139>
D	H01L 2224/7925	<administrative transfer to H10W 72/07141>
D	H01L 2224/79251	<administrative transfer to H10W 72/07141>
D	H01L 2224/79252	<administrative transfer to H10W 72/07141>
D	H01L 2224/79253	<administrative transfer to H10W 72/07141>
D	H01L 2224/7926	<administrative transfer to H10W 72/07141>
D	H01L 2224/79261	<administrative transfer to H10W 72/07141>
D	H01L 2224/79262	<administrative transfer to H10W 72/07141>
D	H01L 2224/79263	<administrative transfer to H10W 72/07141>
D	H01L 2224/79264	<administrative transfer to H10W 72/07141>
D	H01L 2224/79265	<administrative transfer to H10W 72/07141>
D	H01L 2224/79266	<administrative transfer to H10W 72/07141>
D	H01L 2224/79267	<administrative transfer to H10W 72/07141>
D	H01L 2224/79268	<administrative transfer to H10W 72/07141>
D	H01L 2224/79269	<administrative transfer to H10W 72/07141>
D	H01L 2224/7927	<administrative transfer to H10W 72/07141>
D	H01L 2224/79271	<administrative transfer to H10W 72/07141>
D	H01L 2224/79272	<administrative transfer to H10W 72/07141>
D	H01L 2224/7928	<administrative transfer to H10W 72/07141>
D	H01L 2224/79281	<administrative transfer to H10W 72/07141>
D	H01L 2224/79282	<administrative transfer to H10W 72/07141>
D	H01L 2224/79283	<administrative transfer to H10W 72/07141>
D	H01L 2224/793	<administrative transfer to H10W 72/07141>
D	H01L 2224/79301	<administrative transfer to H10W 72/07141>
D	H01L 2224/79302	<administrative transfer to H10W 72/07141>
D	H01L 2224/79303	<administrative transfer to H10W 72/07141>
D	H01L 2224/79304	<administrative transfer to H10W 72/07141>
D	H01L 2224/79305	<administrative transfer to H10W 72/07141>
D	H01L 2224/7931	<administrative transfer to H10W 72/07141>
D	H01L 2224/79312	<administrative transfer to H10W 72/07141>
D	H01L 2224/79313	<administrative transfer to H10W 72/07141>
D	H01L 2224/79314	<administrative transfer to H10W 72/07141>
D	H01L 2224/79315	<administrative transfer to H10W 72/07141>
D	H01L 2224/79316	<administrative transfer to H10W 72/07141>
D	H01L 2224/79317	<administrative transfer to H10W 72/07141>
D	H01L 2224/79318	<administrative transfer to H10W 72/07141>
D	H01L 2224/7932	<administrative transfer to H10W 72/07141>
D	H01L 2224/79343	<administrative transfer to H10W 72/07141>
D	H01L 2224/79344	<administrative transfer to H10W 72/07141>
D	H01L 2224/79345	<administrative transfer to H10W 72/07141>
D	H01L 2224/79346	<administrative transfer to H10W 72/07141>
D	H01L 2224/79347	<administrative transfer to H10W 72/07141>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/79348	<administrative transfer to H10W 72/07141>
D	H01L 2224/79349	<administrative transfer to H10W 72/07141>
D	H01L 2224/7935	<administrative transfer to H10W 72/07141>
D	H01L 2224/79351	<administrative transfer to H10W 72/07141>
D	H01L 2224/79352	<administrative transfer to H10W 72/07141>
D	H01L 2224/79353	<administrative transfer to H10W 72/07141>
D	H01L 2224/79354	<administrative transfer to H10W 72/07141>
D	H01L 2224/79355	<administrative transfer to H10W 72/07141>
D	H01L 2224/795	<administrative transfer to H10W 72/07152>
D	H01L 2224/79501	<administrative transfer to H10W 72/07152>
D	H01L 2224/79502	<administrative transfer to H10W 72/07152>
D	H01L 2224/7955	<administrative transfer to H10W 72/07163>
D	H01L 2224/796	<administrative transfer to H10W 72/07168>
D	H01L 2224/79601	<administrative transfer to H10W 72/07168>
D	H01L 2224/79611	<administrative transfer to H10W 72/07168>
D	H01L 2224/79621	<administrative transfer to H10W 72/07168>
D	H01L 2224/7965	<administrative transfer to H10W 72/07173>
D	H01L 2224/79651	<administrative transfer to H10W 72/07173>
D	H01L 2224/79652	<administrative transfer to H10W 72/07173>
D	H01L 2224/79653	<administrative transfer to H10W 72/07173>
D	H01L 2224/79654	<administrative transfer to H10W 72/07173>
D	H01L 2224/79655	<administrative transfer to H10W 72/07173>
D	H01L 2224/797	<administrative transfer to H10W 72/07178>
D	H01L 2224/79701	<administrative transfer to H10W 72/07178>
D	H01L 2224/79702	<administrative transfer to H10W 72/07178>
D	H01L 2224/79703	<administrative transfer to H10W 72/07178>
D	H01L 2224/79704	<administrative transfer to H10W 72/07178>
D	H01L 2224/79705	<administrative transfer to H10W 72/07178>
D	H01L 2224/79723	<administrative transfer to H10W 72/07178>
D	H01L 2224/79724	<administrative transfer to H10W 72/07178>
D	H01L 2224/79725	<administrative transfer to H10W 72/07178>
D	H01L 2224/79733	<administrative transfer to H10W 72/07178>
D	H01L 2224/79734	<administrative transfer to H10W 72/07178>
D	H01L 2224/79735	<administrative transfer to H10W 72/07178>
D	H01L 2224/79743	<administrative transfer to H10W 72/07178>
D	H01L 2224/79744	<administrative transfer to H10W 72/07178>
D	H01L 2224/79745	<administrative transfer to H10W 72/07178>
D	H01L 2224/79753	<administrative transfer to H10W 72/07178>
D	H01L 2224/79754	<administrative transfer to H10W 72/07178>
D	H01L 2224/79755	<administrative transfer to H10W 72/07178>
D	H01L 2224/79756	<administrative transfer to H10W 72/07178>
D	H01L 2224/798	<administrative transfer to H10W 72/07173>
D	H01L 2224/79801	<administrative transfer to H10W 72/07173>
D	H01L 2224/79802	<administrative transfer to H10W 72/07173>
D	H01L 2224/79803	<administrative transfer to H10W 72/07173>
D	H01L 2224/79804	<administrative transfer to H10W 72/07173>
D	H01L 2224/79821	<administrative transfer to H10W 72/07173>
D	H01L 2224/79822	<administrative transfer to H10W 72/07173>
D	H01L 2224/79823	<administrative transfer to H10W 72/07173>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/79824	<administrative transfer to H10W 72/07173>
D	H01L 2224/79841	<administrative transfer to H10W 72/07173>
D	H01L 2224/79842	<administrative transfer to H10W 72/07173>
D	H01L 2224/79843	<administrative transfer to H10W 72/07173>
D	H01L 2224/799	<administrative transfer to H10W 72/07183>
D	H01L 2224/79901	<administrative transfer to H10W 72/07183>
D	H01L 2224/7992	<administrative transfer to H10W 72/07183>
D	H01L 2224/79925	<administrative transfer to H10W 72/07183>
D	H01L 2224/7995	<administrative transfer to H10W 72/07131>
D	H01L 2224/7998	<administrative transfer to H10W 72/0711>
D	H01L 2224/79981	<administrative transfer to H10W 72/07188>
D	H01L 2224/79982	<administrative transfer to H10W 72/07188>
D	H01L 2224/79983	<administrative transfer to H10W 72/07188>
D	H01L 2224/79984	<administrative transfer to H10W 72/07188>
D	H01L 2224/79985	<administrative transfer to H10W 72/07188>
D	H01L 2224/79986	<administrative transfer to H10W 72/07188>
D	H01L 2224/79987	<administrative transfer to H10W 72/07188>
D	H01L 2224/79988	<administrative transfer to H10W 72/07188>
D	H01L 2224/7999	<administrative transfer to H10W 72/0711>
D	H01L 2224/80	<administrative transfer to H10W 99/00>
D	H01L 2224/80001	<administrative transfer to H10W 80/00>
D	H01L 2224/80003	<administrative transfer to H10W 80/211>
D	H01L 2224/80004	<administrative transfer to H10W 80/211>
D	H01L 2224/80006	<administrative transfer to H10W 80/211>
D	H01L 2224/80007	<administrative transfer to H10W 80/211>
D	H01L 2224/80009	<administrative transfer to H10W 80/011>
D	H01L 2224/8001	<administrative transfer to H10W 80/016>
D	H01L 2224/80011	<administrative transfer to H10W 80/016>
D	H01L 2224/80012	<administrative transfer to H10W 80/016>
D	H01L 2224/80013	<administrative transfer to H10W 80/016>
D	H01L 2224/80014	<administrative transfer to H10W 80/016>
D	H01L 2224/80019	<administrative transfer to H10W 80/016>
D	H01L 2224/8002	<administrative transfer to H10W 80/023>
D	H01L 2224/80024	<administrative transfer to H10W 80/011>
D	H01L 2224/8003	<administrative transfer to H10W 80/031>
D	H01L 2224/80031	<administrative transfer to H10W 80/033>
D	H01L 2224/80035	<administrative transfer to H10W 80/035>
D	H01L 2224/80037	<administrative transfer to H10W 80/035>
D	H01L 2224/80039	<administrative transfer to H10W 80/035>
D	H01L 2224/80041	<administrative transfer to H10W 80/035>
D	H01L 2224/80047	<administrative transfer to H10W 80/037>
D	H01L 2224/80048	<administrative transfer to H10W 80/041>
D	H01L 2224/80051	<administrative transfer to H10W 80/011>
D	H01L 2224/80052	<administrative transfer to H10W 80/011>
D	H01L 2224/80053	<administrative transfer to H10W 80/102>
D	H01L 2224/80054	<administrative transfer to H10W 80/102>
D	H01L 2224/80055	<administrative transfer to H10W 80/102>
D	H01L 2224/80065	<administrative transfer to H10W 80/102>
D	H01L 2224/80075	<administrative transfer to H10W 80/102>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/80085	<administrative transfer to H10W 80/102>
D	H01L 2224/8009	<administrative transfer to H10W 80/102>
D	H01L 2224/80091	<administrative transfer to H10W 80/102>
D	H01L 2224/80092	<administrative transfer to H10W 80/102>
D	H01L 2224/80093	<administrative transfer to H10W 80/102>
D	H01L 2224/80095	<administrative transfer to H10W 80/102>
D	H01L 2224/80096	<administrative transfer to H10W 80/102>
D	H01L 2224/80097	<administrative transfer to H10W 80/102>
D	H01L 2224/80098	<administrative transfer to H10W 80/102>
D	H01L 2224/80099	<administrative transfer to H10W 80/102>
D	H01L 2224/8011	<administrative transfer to H10W 80/011>
D	H01L 2224/8012	<administrative transfer to H10W 80/161>
D	H01L 2224/80121	<administrative transfer to H10W 80/163>
D	H01L 2224/80122	<administrative transfer to H10W 80/163>
D	H01L 2224/80123	<administrative transfer to H10W 80/163>
D	H01L 2224/80125	<administrative transfer to H10W 80/163>
D	H01L 2224/80127	<administrative transfer to H10W 80/163>
D	H01L 2224/80129	<administrative transfer to H10W 80/163>
D	H01L 2224/8013	<administrative transfer to H10W 80/163>
D	H01L 2224/80132	<administrative transfer to H10W 80/163>
D	H01L 2224/80136	<administrative transfer to H10W 80/168>
D	H01L 2224/80138	<administrative transfer to H10W 80/168>
D	H01L 2224/80139	<administrative transfer to H10W 80/168>
D	H01L 2224/8014	<administrative transfer to H10W 80/168>
D	H01L 2224/80141	<administrative transfer to H10W 80/168>
D	H01L 2224/80143	<administrative transfer to H10W 80/165>
D	H01L 2224/80148	<administrative transfer to H10W 80/161>
D	H01L 2224/80149	<administrative transfer to H10W 80/161>
D	H01L 2224/8015	<administrative transfer to H10W 80/161>
D	H01L 2224/8016	<administrative transfer to H10W 80/161>
D	H01L 2224/80169	<administrative transfer to H10W 80/161>
D	H01L 2224/8017	<administrative transfer to H10W 80/161>
D	H01L 2224/8018	<administrative transfer to H10W 80/161>
D	H01L 2224/8019	<administrative transfer to H10W 80/011>
D	H01L 2224/80194	<administrative transfer to H10W 80/011>
D	H01L 2224/802	<administrative transfer to H10W 80/331>
D	H01L 2224/80201	<administrative transfer to H10W 80/333>
D	H01L 2224/80203	<administrative transfer to H10W 80/334>
D	H01L 2224/80204	<administrative transfer to H10W 80/334>
D	H01L 2224/80205	<administrative transfer to H10W 80/335>
D	H01L 2224/80206	<administrative transfer to H10W 80/335>
D	H01L 2224/80207	<administrative transfer to H10W 80/335>
D	H01L 2224/80209	<administrative transfer to H10W 80/335>
D	H01L 2224/80211	<administrative transfer to H10W 80/335>
D	H01L 2224/80213	<administrative transfer to H10W 80/337>
D	H01L 2224/80215	<administrative transfer to H10W 80/337>
D	H01L 2224/8022	<administrative transfer to H10W 80/338>
D	H01L 2224/80222	<administrative transfer to H10W 80/338>
D	H01L 2224/80224	<administrative transfer to H10W 80/338>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/8023	<administrative transfer to H10W 80/338>
D	H01L 2224/80232	<administrative transfer to H10W 80/331>
D	H01L 2224/80234	<administrative transfer to H10W 80/339>
D	H01L 2224/80236	<administrative transfer to H10W 80/331>
D	H01L 2224/80237	<administrative transfer to H10W 80/338>
D	H01L 2224/80238	<administrative transfer to H10W 80/331>
D	H01L 2224/8034	<administrative transfer to H10W 72/90>
D	H01L 2224/80345	<administrative transfer to H10W 72/931>
D	H01L 2224/80355	<administrative transfer to H10W 72/923>
D	H01L 2224/80357	<administrative transfer to H10W 72/941>
D	H01L 2224/80359	<administrative transfer to H10W 72/951>
D	H01L 2224/8036	<administrative transfer to H10W 80/011>
D	H01L 2224/80365	<administrative transfer to H10W 72/931>
D	H01L 2224/80375	<administrative transfer to H10W 80/023>
D	H01L 2224/80379	<administrative transfer to H10W 72/951>
D	H01L 2224/8038	<administrative transfer to H10W 80/011>
D	H01L 2224/80385	<administrative transfer to H10W 72/931>
D	H01L 2224/80395	<administrative transfer to H10W 80/023>
D	H01L 2224/80399	<administrative transfer to H10W 72/951>
D	H01L 2224/804	<administrative transfer to H10W 72/952>
D	H01L 2224/80401	<administrative transfer to H10W 72/952>
D	H01L 2224/80405	<administrative transfer to H10W 72/952>
D	H01L 2224/80409	<administrative transfer to H10W 72/952>
D	H01L 2224/80411	<administrative transfer to H10W 72/952>
D	H01L 2224/80413	<administrative transfer to H10W 72/952>
D	H01L 2224/80414	<administrative transfer to H10W 72/952>
D	H01L 2224/80416	<administrative transfer to H10W 72/952>
D	H01L 2224/80417	<administrative transfer to H10W 72/952>
D	H01L 2224/80418	<administrative transfer to H10W 72/952>
D	H01L 2224/8042	<administrative transfer to H10W 72/952>
D	H01L 2224/80423	<administrative transfer to H10W 72/952>
D	H01L 2224/80424	<administrative transfer to H10W 72/952>
D	H01L 2224/80438	<administrative transfer to H10W 72/952>
D	H01L 2224/80439	<administrative transfer to H10W 72/952>
D	H01L 2224/80444	<administrative transfer to H10W 72/952>
D	H01L 2224/80447	<administrative transfer to H10W 72/952>
D	H01L 2224/80449	<administrative transfer to H10W 72/952>
D	H01L 2224/80455	<administrative transfer to H10W 72/952>
D	H01L 2224/80457	<administrative transfer to H10W 72/952>
D	H01L 2224/8046	<administrative transfer to H10W 72/952>
D	H01L 2224/80463	<administrative transfer to H10W 72/952>
D	H01L 2224/80464	<administrative transfer to H10W 72/952>
D	H01L 2224/80466	<administrative transfer to H10W 72/952>
D	H01L 2224/80469	<administrative transfer to H10W 72/952>
D	H01L 2224/8047	<administrative transfer to H10W 72/952>
D	H01L 2224/80471	<administrative transfer to H10W 72/952>
D	H01L 2224/80472	<administrative transfer to H10W 72/952>
D	H01L 2224/80473	<administrative transfer to H10W 72/952>
D	H01L 2224/80476	<administrative transfer to H10W 72/952>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/80478	<administrative transfer to H10W 72/952>
D	H01L 2224/80479	<administrative transfer to H10W 72/952>
D	H01L 2224/8048	<administrative transfer to H10W 72/952>
D	H01L 2224/80481	<administrative transfer to H10W 72/952>
D	H01L 2224/80483	<administrative transfer to H10W 72/952>
D	H01L 2224/80484	<administrative transfer to H10W 72/952>
D	H01L 2224/80486	<administrative transfer to H10W 72/953>
D	H01L 2224/80487	<administrative transfer to H10W 72/953>
D	H01L 2224/80488	<administrative transfer to H10W 72/953>
D	H01L 2224/8049	<administrative transfer to H10W 72/953>
D	H01L 2224/80491	<administrative transfer to H10W 72/953>
D	H01L 2224/80493	<administrative transfer to H10W 72/953>
D	H01L 2224/80494	<administrative transfer to H10W 72/953>
D	H01L 2224/80495	<administrative transfer to H10W 72/953>
D	H01L 2224/80498	<administrative transfer to H10W 72/951>
D	H01L 2224/80499	<administrative transfer to H10W 72/951>
D	H01L 2224/805	<administrative transfer to H10W 72/952>
D	H01L 2224/80501	<administrative transfer to H10W 72/952>
D	H01L 2224/80505	<administrative transfer to H10W 72/952>
D	H01L 2224/80509	<administrative transfer to H10W 72/952>
D	H01L 2224/80511	<administrative transfer to H10W 72/952>
D	H01L 2224/80513	<administrative transfer to H10W 72/952>
D	H01L 2224/80514	<administrative transfer to H10W 72/952>
D	H01L 2224/80516	<administrative transfer to H10W 72/952>
D	H01L 2224/80517	<administrative transfer to H10W 72/952>
D	H01L 2224/80518	<administrative transfer to H10W 72/952>
D	H01L 2224/8052	<administrative transfer to H10W 72/952>
D	H01L 2224/80523	<administrative transfer to H10W 72/952>
D	H01L 2224/80524	<administrative transfer to H10W 72/952>
D	H01L 2224/80538	<administrative transfer to H10W 72/952>
D	H01L 2224/80539	<administrative transfer to H10W 72/952>
D	H01L 2224/80544	<administrative transfer to H10W 72/952>
D	H01L 2224/80547	<administrative transfer to H10W 72/952>
D	H01L 2224/80549	<administrative transfer to H10W 72/952>
D	H01L 2224/80555	<administrative transfer to H10W 72/952>
D	H01L 2224/80557	<administrative transfer to H10W 72/952>
D	H01L 2224/8056	<administrative transfer to H10W 72/952>
D	H01L 2224/80563	<administrative transfer to H10W 72/952>
D	H01L 2224/80564	<administrative transfer to H10W 72/952>
D	H01L 2224/80566	<administrative transfer to H10W 72/952>
D	H01L 2224/80569	<administrative transfer to H10W 72/952>
D	H01L 2224/8057	<administrative transfer to H10W 72/952>
D	H01L 2224/80571	<administrative transfer to H10W 72/952>
D	H01L 2224/80572	<administrative transfer to H10W 72/952>
D	H01L 2224/80573	<administrative transfer to H10W 72/952>
D	H01L 2224/80576	<administrative transfer to H10W 72/952>
D	H01L 2224/80578	<administrative transfer to H10W 72/952>
D	H01L 2224/80579	<administrative transfer to H10W 72/952>
D	H01L 2224/8058	<administrative transfer to H10W 72/952>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/80581	<administrative transfer to H10W 72/952>
D	H01L 2224/80583	<administrative transfer to H10W 72/952>
D	H01L 2224/80584	<administrative transfer to H10W 72/952>
D	H01L 2224/80586	<administrative transfer to H10W 72/953>
D	H01L 2224/80587	<administrative transfer to H10W 72/953>
D	H01L 2224/80588	<administrative transfer to H10W 72/953>
D	H01L 2224/8059	<administrative transfer to H10W 72/953>
D	H01L 2224/80591	<administrative transfer to H10W 72/953>
D	H01L 2224/80593	<administrative transfer to H10W 72/953>
D	H01L 2224/80594	<administrative transfer to H10W 72/953>
D	H01L 2224/80595	<administrative transfer to H10W 72/953>
D	H01L 2224/80598	<administrative transfer to H10W 72/951>
D	H01L 2224/80599	<administrative transfer to H10W 72/951>
D	H01L 2224/806	<administrative transfer to H10W 72/952>
D	H01L 2224/80601	<administrative transfer to H10W 72/952>
D	H01L 2224/80605	<administrative transfer to H10W 72/952>
D	H01L 2224/80609	<administrative transfer to H10W 72/952>
D	H01L 2224/80611	<administrative transfer to H10W 72/952>
D	H01L 2224/80613	<administrative transfer to H10W 72/952>
D	H01L 2224/80614	<administrative transfer to H10W 72/952>
D	H01L 2224/80616	<administrative transfer to H10W 72/952>
D	H01L 2224/80617	<administrative transfer to H10W 72/952>
D	H01L 2224/80618	<administrative transfer to H10W 72/952>
D	H01L 2224/8062	<administrative transfer to H10W 72/952>
D	H01L 2224/80623	<administrative transfer to H10W 72/952>
D	H01L 2224/80624	<administrative transfer to H10W 72/952>
D	H01L 2224/80638	<administrative transfer to H10W 72/952>
D	H01L 2224/80639	<administrative transfer to H10W 72/952>
D	H01L 2224/80644	<administrative transfer to H10W 72/952>
D	H01L 2224/80647	<administrative transfer to H10W 72/952>
D	H01L 2224/80649	<administrative transfer to H10W 72/952>
D	H01L 2224/80655	<administrative transfer to H10W 72/952>
D	H01L 2224/80657	<administrative transfer to H10W 72/952>
D	H01L 2224/8066	<administrative transfer to H10W 72/952>
D	H01L 2224/80663	<administrative transfer to H10W 72/952>
D	H01L 2224/80664	<administrative transfer to H10W 72/952>
D	H01L 2224/80666	<administrative transfer to H10W 72/952>
D	H01L 2224/80669	<administrative transfer to H10W 72/952>
D	H01L 2224/8067	<administrative transfer to H10W 72/952>
D	H01L 2224/80671	<administrative transfer to H10W 72/952>
D	H01L 2224/80672	<administrative transfer to H10W 72/952>
D	H01L 2224/80673	<administrative transfer to H10W 72/952>
D	H01L 2224/80676	<administrative transfer to H10W 72/952>
D	H01L 2224/80678	<administrative transfer to H10W 72/952>
D	H01L 2224/80679	<administrative transfer to H10W 72/952>
D	H01L 2224/8068	<administrative transfer to H10W 72/952>
D	H01L 2224/80681	<administrative transfer to H10W 72/952>
D	H01L 2224/80683	<administrative transfer to H10W 72/952>
D	H01L 2224/80684	<administrative transfer to H10W 72/952>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/80686	<administrative transfer to H10W 72/953>
D	H01L 2224/80687	<administrative transfer to H10W 72/953>
D	H01L 2224/80688	<administrative transfer to H10W 72/953>
D	H01L 2224/8069	<administrative transfer to H10W 72/953>
D	H01L 2224/80691	<administrative transfer to H10W 72/953>
D	H01L 2224/80693	<administrative transfer to H10W 72/953>
D	H01L 2224/80694	<administrative transfer to H10W 72/953>
D	H01L 2224/80695	<administrative transfer to H10W 72/953>
D	H01L 2224/80698	<administrative transfer to H10W 72/951>
D	H01L 2224/80699	<administrative transfer to H10W 72/951>
D	H01L 2224/807	<administrative transfer to H10W 72/952>
D	H01L 2224/80701	<administrative transfer to H10W 72/952>
D	H01L 2224/80705	<administrative transfer to H10W 72/952>
D	H01L 2224/80709	<administrative transfer to H10W 72/952>
D	H01L 2224/80711	<administrative transfer to H10W 72/952>
D	H01L 2224/80713	<administrative transfer to H10W 72/952>
D	H01L 2224/80714	<administrative transfer to H10W 72/952>
D	H01L 2224/80716	<administrative transfer to H10W 72/952>
D	H01L 2224/80717	<administrative transfer to H10W 72/952>
D	H01L 2224/80718	<administrative transfer to H10W 72/952>
D	H01L 2224/8072	<administrative transfer to H10W 72/952>
D	H01L 2224/80723	<administrative transfer to H10W 72/952>
D	H01L 2224/80724	<administrative transfer to H10W 72/952>
D	H01L 2224/80738	<administrative transfer to H10W 72/952>
D	H01L 2224/80739	<administrative transfer to H10W 72/952>
D	H01L 2224/80744	<administrative transfer to H10W 72/952>
D	H01L 2224/80747	<administrative transfer to H10W 72/952>
D	H01L 2224/80749	<administrative transfer to H10W 72/952>
D	H01L 2224/80755	<administrative transfer to H10W 72/952>
D	H01L 2224/80757	<administrative transfer to H10W 72/952>
D	H01L 2224/8076	<administrative transfer to H10W 72/952>
D	H01L 2224/80763	<administrative transfer to H10W 72/952>
D	H01L 2224/80764	<administrative transfer to H10W 72/952>
D	H01L 2224/80766	<administrative transfer to H10W 72/952>
D	H01L 2224/80769	<administrative transfer to H10W 72/952>
D	H01L 2224/8077	<administrative transfer to H10W 72/952>
D	H01L 2224/80771	<administrative transfer to H10W 72/952>
D	H01L 2224/80772	<administrative transfer to H10W 72/952>
D	H01L 2224/80773	<administrative transfer to H10W 72/952>
D	H01L 2224/80776	<administrative transfer to H10W 72/952>
D	H01L 2224/80778	<administrative transfer to H10W 72/952>
D	H01L 2224/80779	<administrative transfer to H10W 72/952>
D	H01L 2224/8078	<administrative transfer to H10W 72/952>
D	H01L 2224/80781	<administrative transfer to H10W 72/952>
D	H01L 2224/80783	<administrative transfer to H10W 72/952>
D	H01L 2224/80784	<administrative transfer to H10W 72/952>
D	H01L 2224/80786	<administrative transfer to H10W 72/953>
D	H01L 2224/80787	<administrative transfer to H10W 72/953>
D	H01L 2224/80788	<administrative transfer to H10W 72/953>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/8079	<administrative transfer to H10W 72/953>
D	H01L 2224/80791	<administrative transfer to H10W 72/953>
D	H01L 2224/80793	<administrative transfer to H10W 72/953>
D	H01L 2224/80794	<administrative transfer to H10W 72/953>
D	H01L 2224/80795	<administrative transfer to H10W 72/953>
D	H01L 2224/80798	<administrative transfer to H10W 72/951>
D	H01L 2224/80799	<administrative transfer to H10W 72/951>
D	H01L 2224/808	<administrative transfer to H10W 72/071>
D	H01L 2224/80801	<administrative transfer to H10W 72/07236>
D	H01L 2224/80805	<administrative transfer to H10W 72/07236>
D	H01L 2224/8081	<administrative transfer to H10W 72/07236>
D	H01L 2224/80815	<administrative transfer to H10W 72/07236>
D	H01L 2224/8082	<administrative transfer to H10W 72/07236>
D	H01L 2224/80825	<administrative transfer to H10W 72/07236>
D	H01L 2224/8083	<administrative transfer to H10W 72/07236>
D	H01L 2224/8084	<administrative transfer to H10W 72/07231>
D	H01L 2224/8085	<administrative transfer to H10W 72/07337>
D	H01L 2224/80855	<administrative transfer to H10W 72/07338>
D	H01L 2224/80856	<administrative transfer to H10W 72/07338>
D	H01L 2224/80859	<administrative transfer to H10W 72/07338>
D	H01L 2224/80862	<administrative transfer to H10W 72/07338>
D	H01L 2224/80865	<administrative transfer to H10W 72/07338>
D	H01L 2224/80868	<administrative transfer to H10W 72/07338>
D	H01L 2224/80871	<administrative transfer to H10W 72/07338>
D	H01L 2224/80874	<administrative transfer to H10W 72/07338>
D	H01L 2224/80877	<administrative transfer to H10W 72/07338>
D	H01L 2224/8088	<administrative transfer to H10W 72/07339>
D	H01L 2224/80885	<administrative transfer to H10W 72/07337>
D	H01L 2224/8089	<administrative transfer to H10W 72/073>
D	H01L 2224/80893	<administrative transfer to H10W 80/341>
D	H01L 2224/80894	<administrative transfer to H10W 80/301>
D	H01L 2224/80895	<administrative transfer to H10W 80/312>
D	H01L 2224/80896	<administrative transfer to H10W 80/327>
D	H01L 2224/80897	<administrative transfer to H10W 72/071>
D	H01L 2224/80898	<administrative transfer to H10W 72/071>
D	H01L 2224/80899	<administrative transfer to H10W 72/071>
D	H01L 2224/809	<administrative transfer to H10W 72/071>
D	H01L 2224/80901	<administrative transfer to H10W 72/071>
D	H01L 2224/80902	<administrative transfer to H10W 72/071>
D	H01L 2224/80903	<administrative transfer to H10W 72/071>
D	H01L 2224/80904	<administrative transfer to H10W 72/071>
D	H01L 2224/80905	<administrative transfer to H10W 80/301>
D	H01L 2224/80906	<administrative transfer to H10W 80/301>
D	H01L 2224/80907	<administrative transfer to H10W 80/301>
D	H01L 2224/80908	<administrative transfer to H10W 80/301>
D	H01L 2224/80909	<administrative transfer to H10W 72/019>
D	H01L 2224/8091	<administrative transfer to H10W 72/01971>
D	H01L 2224/80911	<administrative transfer to H10W 72/01971>
D	H01L 2224/80912	<administrative transfer to H10W 72/01971>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/80913	<administrative transfer to H10W 72/01971>
D	H01L 2224/80914	<administrative transfer to H10W 72/01971>
D	H01L 2224/80919	<administrative transfer to H10W 72/01971>
D	H01L 2224/8092	<administrative transfer to H10W 72/019>
D	H01L 2224/8093	<administrative transfer to H10W 72/01951>
D	H01L 2224/80931	<administrative transfer to H10W 72/01953>
D	H01L 2224/80935	<administrative transfer to H10W 72/01951>
D	H01L 2224/80937	<administrative transfer to H10W 72/01951>
D	H01L 2224/80939	<administrative transfer to H10W 72/01951>
D	H01L 2224/80941	<administrative transfer to H10W 72/01951>
D	H01L 2224/80943	<administrative transfer to H10W 72/01951>
D	H01L 2224/80945	<administrative transfer to H10W 72/01951>
D	H01L 2224/80947	<administrative transfer to H10W 72/01951>
D	H01L 2224/80948	<administrative transfer to H10W 72/019>
D	H01L 2224/80951	<administrative transfer to H10W 72/019>
D	H01L 2224/80986	<administrative transfer to H10W 72/019>
D	H01L 2224/81	<administrative transfer to H10W 72/072>
D	H01L 2224/81001	<administrative transfer to H10W 72/07204>
D	H01L 2224/81002	<administrative transfer to H10W 72/07204>
D	H01L 2224/81005	<administrative transfer to H10W 72/07207>
D	H01L 2224/81007	<administrative transfer to H10W 72/07202>
D	H01L 2224/81009	<administrative transfer to H10W 72/012>
D	H01L 2224/8101	<administrative transfer to H10W 72/01271 and H10W 72/072 simultaneously>
D	H01L 2224/81011	<administrative transfer to H10W 72/01271 and H10W 72/072 simultaneously>
D	H01L 2224/81012	<administrative transfer to H10W 72/01271 and H10W 72/072 simultaneously>
D	H01L 2224/81013	<administrative transfer to H10W 72/01271 and H10W 72/072 simultaneously>
D	H01L 2224/81014	<administrative transfer to H10W 72/01271 and H10W 72/072 simultaneously>
D	H01L 2224/81019	<administrative transfer to H10W 72/01271 and H10W 72/072 simultaneously>
D	H01L 2224/8102	<administrative transfer to H10W 72/01215 and H10W 72/072 simultaneously>
D	H01L 2224/81022	<administrative transfer to H10W 72/07211>
D	H01L 2224/81024	<administrative transfer to H10W 72/07211>
D	H01L 2224/81026	<administrative transfer to H10W 72/07211>
D	H01L 2224/8103	<administrative transfer to H10W 72/01251 and H10W 72/072 simultaneously>
D	H01L 2224/81031	<administrative transfer to H10W 72/01253 and H10W 72/072 simultaneously>
D	H01L 2224/81035	<administrative transfer to H10W 72/01257 and H10W 72/072 simultaneously>
D	H01L 2224/81037	<administrative transfer to H10W 72/01257 and H10W 72/072 simultaneously>
D	H01L 2224/81039	<administrative transfer to H10W 72/01257 and H10W 72/072 simultaneously>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/81041	<administrative transfer to H10W 72/01257 and H10W 72/072 simultaneously>
D	H01L 2224/81047	<administrative transfer to H10W 72/01257 and H10W 72/072 simultaneously>
D	H01L 2224/81048	<administrative transfer to H10W 72/012 and H10W 72/072 simultaneously>
D	H01L 2224/81051	<administrative transfer to H10W 72/012 and H10W 72/072 simultaneously>
D	H01L 2224/81052	<administrative transfer to H10W 72/072>
D	H01L 2224/81053	<administrative transfer to H10W 72/016>
D	H01L 2224/81054	<administrative transfer to H10W 72/016>
D	H01L 2224/81055	<administrative transfer to H10W 72/016>
D	H01L 2224/81065	<administrative transfer to H10W 72/016>
D	H01L 2224/81075	<administrative transfer to H10W 72/016>
D	H01L 2224/81085	<administrative transfer to H10W 72/016>
D	H01L 2224/8109	<administrative transfer to H10W 72/016>
D	H01L 2224/81091	<administrative transfer to H10W 72/016>
D	H01L 2224/81092	<administrative transfer to H10W 72/016>
D	H01L 2224/81093	<administrative transfer to H10W 72/016>
D	H01L 2224/81095	<administrative transfer to H10W 72/016>
D	H01L 2224/81096	<administrative transfer to H10W 72/016>
D	H01L 2224/81097	<administrative transfer to H10W 72/016>
D	H01L 2224/81098	<administrative transfer to H10W 72/016>
D	H01L 2224/81099	<administrative transfer to H10W 72/016>
D	H01L 2224/811	<administrative transfer to H10W 72/01212 and H10W 72/072 simultaneously>
D	H01L 2224/81101	<administrative transfer to H10W 72/01212 and H10W 72/072 simultaneously>
D	H01L 2224/8111	<administrative transfer to H10W 72/072>
D	H01L 2224/8112	<administrative transfer to H10W 72/07221>
D	H01L 2224/81121	<administrative transfer to H10W 72/07223>
D	H01L 2224/81122	<administrative transfer to H10W 72/07223>
D	H01L 2224/81123	<administrative transfer to H10W 72/07223>
D	H01L 2224/81125	<administrative transfer to H10W 72/07223>
D	H01L 2224/81127	<administrative transfer to H10W 72/07223>
D	H01L 2224/81129	<administrative transfer to H10W 72/07223>
D	H01L 2224/8113	<administrative transfer to H10W 72/07223>
D	H01L 2224/81132	<administrative transfer to H10W 72/07223>
D	H01L 2224/81136	<administrative transfer to H10W 72/07227>
D	H01L 2224/81138	<administrative transfer to H10W 72/07227>
D	H01L 2224/81139	<administrative transfer to H10W 72/07227>
D	H01L 2224/8114	<administrative transfer to H10W 72/07227>
D	H01L 2224/81141	<administrative transfer to H10W 72/07227>
D	H01L 2224/81143	<administrative transfer to H10W 72/07221>
D	H01L 2224/81148	<administrative transfer to H10W 72/072>
D	H01L 2224/81149	<administrative transfer to H10W 72/072>
D	H01L 2224/8115	<administrative transfer to H10W 72/072>
D	H01L 2224/8116	<administrative transfer to H10W 72/072>
D	H01L 2224/81169	<administrative transfer to H10W 72/072>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/8117	<administrative transfer to H10W 72/072>
D	H01L 2224/8118	<administrative transfer to H10W 72/072>
D	H01L 2224/8119	<administrative transfer to H10W 72/241 and H10W 72/072 simultaneously>
D	H01L 2224/81191	<administrative transfer to H10W 72/241 and H10W 72/072 simultaneously>
D	H01L 2224/81192	<administrative transfer to H10W 72/241 and H10W 72/072 simultaneously>
D	H01L 2224/81193	<administrative transfer to H10W 72/241 and H10W 72/072 simultaneously>
D	H01L 2224/81194	<administrative transfer to H10W 72/248 and H10W 72/072 simultaneously>
D	H01L 2224/812	<administrative transfer to H10W 72/07231>
D	H01L 2224/81201	<administrative transfer to H10W 72/07232>
D	H01L 2224/81203	<administrative transfer to H10W 72/07232>
D	H01L 2224/81204	<administrative transfer to H10W 72/07232>
D	H01L 2224/81205	<administrative transfer to H10W 72/07233>
D	H01L 2224/81206	<administrative transfer to H10W 72/07233>
D	H01L 2224/81207	<administrative transfer to H10W 72/07233>
D	H01L 2224/81208	<administrative transfer to H10W 72/07232>
D	H01L 2224/81209	<administrative transfer to H10W 72/07232>
D	H01L 2224/8121	<administrative transfer to H10W 72/07234>
D	H01L 2224/81211	<administrative transfer to H10W 72/07234>
D	H01L 2224/8122	<administrative transfer to H10W 72/07235>
D	H01L 2224/81222	<administrative transfer to H10W 72/07235>
D	H01L 2224/81224	<administrative transfer to H10W 72/07235>
D	H01L 2224/8123	<administrative transfer to H10W 72/07235>
D	H01L 2224/81232	<administrative transfer to H10W 72/072>
D	H01L 2224/81234	<administrative transfer to H10W 72/072>
D	H01L 2224/81236	<administrative transfer to H10W 72/072>
D	H01L 2224/81237	<administrative transfer to H10W 72/072>
D	H01L 2224/81238	<administrative transfer to H10W 72/072>
D	H01L 2224/8134	<administrative transfer to H10W 72/072>
D	H01L 2224/81345	<administrative transfer to H10W 72/072 and H10W 72/07253 simultaneously>
D	H01L 2224/81355	<administrative transfer to H10W 72/072 and H10W 72/222 simultaneously>
D	H01L 2224/81359	<administrative transfer to H10W 72/072, H10W 72/251 and H10W 72/2528 simultaneously>
D	H01L 2224/8136	<administrative transfer to H10W 72/072>
D	H01L 2224/81365	<administrative transfer to H10W 72/072>
D	H01L 2224/81375	<administrative transfer to H10W 72/072>
D	H01L 2224/81379	<administrative transfer to H10W 72/072>
D	H01L 2224/8138	<administrative transfer to H10W 72/072>
D	H01L 2224/81385	<administrative transfer to H10W 72/072>
D	H01L 2224/81395	<administrative transfer to H10W 72/072>
D	H01L 2224/81399	<administrative transfer to H10W 72/072>
D	H01L 2224/814	<administrative transfer to H10W 72/072>
D	H01L 2224/81401	<administrative transfer to H10W 72/072>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/81405	<administrative transfer to H10W 72/072>
D	H01L 2224/81409	<administrative transfer to H10W 72/072>
D	H01L 2224/81411	<administrative transfer to H10W 72/072>
D	H01L 2224/81413	<administrative transfer to H10W 72/072>
D	H01L 2224/81414	<administrative transfer to H10W 72/072>
D	H01L 2224/81416	<administrative transfer to H10W 72/072>
D	H01L 2224/81417	<administrative transfer to H10W 72/072>
D	H01L 2224/81418	<administrative transfer to H10W 72/072>
D	H01L 2224/8142	<administrative transfer to H10W 72/072>
D	H01L 2224/81423	<administrative transfer to H10W 72/072>
D	H01L 2224/81424	<administrative transfer to H10W 72/072>
D	H01L 2224/81438	<administrative transfer to H10W 72/072>
D	H01L 2224/81439	<administrative transfer to H10W 72/072>
D	H01L 2224/81444	<administrative transfer to H10W 72/072>
D	H01L 2224/81447	<administrative transfer to H10W 72/072>
D	H01L 2224/81449	<administrative transfer to H10W 72/072>
D	H01L 2224/81455	<administrative transfer to H10W 72/072>
D	H01L 2224/81457	<administrative transfer to H10W 72/072>
D	H01L 2224/8146	<administrative transfer to H10W 72/072>
D	H01L 2224/81463	<administrative transfer to H10W 72/072>
D	H01L 2224/81464	<administrative transfer to H10W 72/072>
D	H01L 2224/81466	<administrative transfer to H10W 72/072>
D	H01L 2224/81469	<administrative transfer to H10W 72/072>
D	H01L 2224/8147	<administrative transfer to H10W 72/072>
D	H01L 2224/81471	<administrative transfer to H10W 72/072>
D	H01L 2224/81472	<administrative transfer to H10W 72/072>
D	H01L 2224/81473	<administrative transfer to H10W 72/072>
D	H01L 2224/81476	<administrative transfer to H10W 72/072>
D	H01L 2224/81478	<administrative transfer to H10W 72/072>
D	H01L 2224/81479	<administrative transfer to H10W 72/072>
D	H01L 2224/8148	<administrative transfer to H10W 72/072>
D	H01L 2224/81481	<administrative transfer to H10W 72/072>
D	H01L 2224/81483	<administrative transfer to H10W 72/072>
D	H01L 2224/81484	<administrative transfer to H10W 72/072>
D	H01L 2224/81486	<administrative transfer to H10W 72/072>
D	H01L 2224/81487	<administrative transfer to H10W 72/072>
D	H01L 2224/81488	<administrative transfer to H10W 72/072>
D	H01L 2224/8149	<administrative transfer to H10W 72/072>
D	H01L 2224/81491	<administrative transfer to H10W 72/072>
D	H01L 2224/81493	<administrative transfer to H10W 72/072>
D	H01L 2224/81494	<administrative transfer to H10W 72/072>
D	H01L 2224/81495	<administrative transfer to H10W 72/072>
D	H01L 2224/81498	<administrative transfer to H10W 72/072>
D	H01L 2224/81499	<administrative transfer to H10W 72/072>
D	H01L 2224/815	<administrative transfer to H10W 72/072>
D	H01L 2224/81501	<administrative transfer to H10W 72/072>
D	H01L 2224/81505	<administrative transfer to H10W 72/072>
D	H01L 2224/81509	<administrative transfer to H10W 72/072>
D	H01L 2224/81511	<administrative transfer to H10W 72/072>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/81513	<administrative transfer to H10W 72/072>
D	H01L 2224/81514	<administrative transfer to H10W 72/072>
D	H01L 2224/81516	<administrative transfer to H10W 72/072>
D	H01L 2224/81517	<administrative transfer to H10W 72/072>
D	H01L 2224/81518	<administrative transfer to H10W 72/072>
D	H01L 2224/8152	<administrative transfer to H10W 72/072>
D	H01L 2224/81523	<administrative transfer to H10W 72/072>
D	H01L 2224/81524	<administrative transfer to H10W 72/072>
D	H01L 2224/81538	<administrative transfer to H10W 72/072>
D	H01L 2224/81539	<administrative transfer to H10W 72/072>
D	H01L 2224/81544	<administrative transfer to H10W 72/072>
D	H01L 2224/81547	<administrative transfer to H10W 72/072>
D	H01L 2224/81549	<administrative transfer to H10W 72/072>
D	H01L 2224/81555	<administrative transfer to H10W 72/072>
D	H01L 2224/81557	<administrative transfer to H10W 72/072>
D	H01L 2224/8156	<administrative transfer to H10W 72/072>
D	H01L 2224/81563	<administrative transfer to H10W 72/072>
D	H01L 2224/81564	<administrative transfer to H10W 72/072>
D	H01L 2224/81566	<administrative transfer to H10W 72/072>
D	H01L 2224/81569	<administrative transfer to H10W 72/072>
D	H01L 2224/8157	<administrative transfer to H10W 72/072>
D	H01L 2224/81571	<administrative transfer to H10W 72/072>
D	H01L 2224/81572	<administrative transfer to H10W 72/072>
D	H01L 2224/81573	<administrative transfer to H10W 72/072>
D	H01L 2224/81576	<administrative transfer to H10W 72/072>
D	H01L 2224/81578	<administrative transfer to H10W 72/072>
D	H01L 2224/81579	<administrative transfer to H10W 72/072>
D	H01L 2224/8158	<administrative transfer to H10W 72/072>
D	H01L 2224/81581	<administrative transfer to H10W 72/072>
D	H01L 2224/81583	<administrative transfer to H10W 72/072>
D	H01L 2224/81584	<administrative transfer to H10W 72/072>
D	H01L 2224/81586	<administrative transfer to H10W 72/072>
D	H01L 2224/81587	<administrative transfer to H10W 72/072>
D	H01L 2224/81588	<administrative transfer to H10W 72/072>
D	H01L 2224/8159	<administrative transfer to H10W 72/072>
D	H01L 2224/81591	<administrative transfer to H10W 72/072>
D	H01L 2224/81593	<administrative transfer to H10W 72/072>
D	H01L 2224/81594	<administrative transfer to H10W 72/072>
D	H01L 2224/81595	<administrative transfer to H10W 72/072>
D	H01L 2224/81598	<administrative transfer to H10W 72/072>
D	H01L 2224/81599	<administrative transfer to H10W 72/072>
D	H01L 2224/816	<administrative transfer to H10W 72/072>
D	H01L 2224/81601	<administrative transfer to H10W 72/072>
D	H01L 2224/81605	<administrative transfer to H10W 72/072>
D	H01L 2224/81609	<administrative transfer to H10W 72/072>
D	H01L 2224/81611	<administrative transfer to H10W 72/072>
D	H01L 2224/81613	<administrative transfer to H10W 72/072>
D	H01L 2224/81614	<administrative transfer to H10W 72/072>
D	H01L 2224/81616	<administrative transfer to H10W 72/072>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/81617	<administrative transfer to H10W 72/072>
D	H01L 2224/81618	<administrative transfer to H10W 72/072>
D	H01L 2224/8162	<administrative transfer to H10W 72/072>
D	H01L 2224/81623	<administrative transfer to H10W 72/072>
D	H01L 2224/81624	<administrative transfer to H10W 72/072>
D	H01L 2224/81638	<administrative transfer to H10W 72/072>
D	H01L 2224/81639	<administrative transfer to H10W 72/072>
D	H01L 2224/81644	<administrative transfer to H10W 72/072>
D	H01L 2224/81647	<administrative transfer to H10W 72/072>
D	H01L 2224/81649	<administrative transfer to H10W 72/072>
D	H01L 2224/81655	<administrative transfer to H10W 72/072>
D	H01L 2224/81657	<administrative transfer to H10W 72/072>
D	H01L 2224/8166	<administrative transfer to H10W 72/072>
D	H01L 2224/81663	<administrative transfer to H10W 72/072>
D	H01L 2224/81664	<administrative transfer to H10W 72/072>
D	H01L 2224/81666	<administrative transfer to H10W 72/072>
D	H01L 2224/81669	<administrative transfer to H10W 72/072>
D	H01L 2224/8167	<administrative transfer to H10W 72/072>
D	H01L 2224/81671	<administrative transfer to H10W 72/072>
D	H01L 2224/81672	<administrative transfer to H10W 72/072>
D	H01L 2224/81673	<administrative transfer to H10W 72/072>
D	H01L 2224/81676	<administrative transfer to H10W 72/072>
D	H01L 2224/81678	<administrative transfer to H10W 72/072>
D	H01L 2224/81679	<administrative transfer to H10W 72/072>
D	H01L 2224/8168	<administrative transfer to H10W 72/072>
D	H01L 2224/81681	<administrative transfer to H10W 72/072>
D	H01L 2224/81683	<administrative transfer to H10W 72/072>
D	H01L 2224/81684	<administrative transfer to H10W 72/072>
D	H01L 2224/81686	<administrative transfer to H10W 72/072>
D	H01L 2224/81687	<administrative transfer to H10W 72/072>
D	H01L 2224/81688	<administrative transfer to H10W 72/072>
D	H01L 2224/8169	<administrative transfer to H10W 72/072>
D	H01L 2224/81691	<administrative transfer to H10W 72/072>
D	H01L 2224/81693	<administrative transfer to H10W 72/072>
D	H01L 2224/81694	<administrative transfer to H10W 72/072>
D	H01L 2224/81695	<administrative transfer to H10W 72/072>
D	H01L 2224/81698	<administrative transfer to H10W 72/072>
D	H01L 2224/81699	<administrative transfer to H10W 72/072>
D	H01L 2224/817	<administrative transfer to H10W 72/072>
D	H01L 2224/81701	<administrative transfer to H10W 72/072>
D	H01L 2224/81705	<administrative transfer to H10W 72/072>
D	H01L 2224/81709	<administrative transfer to H10W 72/072>
D	H01L 2224/81711	<administrative transfer to H10W 72/072>
D	H01L 2224/81713	<administrative transfer to H10W 72/072>
D	H01L 2224/81714	<administrative transfer to H10W 72/072>
D	H01L 2224/81716	<administrative transfer to H10W 72/072>
D	H01L 2224/81717	<administrative transfer to H10W 72/072>
D	H01L 2224/81718	<administrative transfer to H10W 72/072>
D	H01L 2224/8172	<administrative transfer to H10W 72/072>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/81723	<administrative transfer to H10W 72/072>
D	H01L 2224/81724	<administrative transfer to H10W 72/072>
D	H01L 2224/81738	<administrative transfer to H10W 72/072>
D	H01L 2224/81739	<administrative transfer to H10W 72/072>
D	H01L 2224/81744	<administrative transfer to H10W 72/072>
D	H01L 2224/81747	<administrative transfer to H10W 72/072>
D	H01L 2224/81749	<administrative transfer to H10W 72/072>
D	H01L 2224/81755	<administrative transfer to H10W 72/072>
D	H01L 2224/81757	<administrative transfer to H10W 72/072>
D	H01L 2224/8176	<administrative transfer to H10W 72/072>
D	H01L 2224/81763	<administrative transfer to H10W 72/072>
D	H01L 2224/81764	<administrative transfer to H10W 72/072>
D	H01L 2224/81766	<administrative transfer to H10W 72/072>
D	H01L 2224/81769	<administrative transfer to H10W 72/072>
D	H01L 2224/8177	<administrative transfer to H10W 72/072>
D	H01L 2224/81771	<administrative transfer to H10W 72/072>
D	H01L 2224/81772	<administrative transfer to H10W 72/072>
D	H01L 2224/81773	<administrative transfer to H10W 72/072>
D	H01L 2224/81776	<administrative transfer to H10W 72/072>
D	H01L 2224/81778	<administrative transfer to H10W 72/072>
D	H01L 2224/81779	<administrative transfer to H10W 72/072>
D	H01L 2224/8178	<administrative transfer to H10W 72/072>
D	H01L 2224/81781	<administrative transfer to H10W 72/072>
D	H01L 2224/81783	<administrative transfer to H10W 72/072>
D	H01L 2224/81784	<administrative transfer to H10W 72/072>
D	H01L 2224/81786	<administrative transfer to H10W 72/072>
D	H01L 2224/81787	<administrative transfer to H10W 72/072>
D	H01L 2224/81788	<administrative transfer to H10W 72/072>
D	H01L 2224/8179	<administrative transfer to H10W 72/072>
D	H01L 2224/81791	<administrative transfer to H10W 72/072>
D	H01L 2224/81793	<administrative transfer to H10W 72/072>
D	H01L 2224/81794	<administrative transfer to H10W 72/072>
D	H01L 2224/81795	<administrative transfer to H10W 72/072>
D	H01L 2224/81798	<administrative transfer to H10W 72/072>
D	H01L 2224/81799	<administrative transfer to H10W 72/072>
D	H01L 2224/818	<administrative transfer to H10W 72/07231>
D	H01L 2224/81801	<administrative transfer to H10W 72/07236>
D	H01L 2224/81805	<administrative transfer to H10W 72/07236>
D	H01L 2224/8181	<administrative transfer to H10W 72/07236>
D	H01L 2224/81815	<administrative transfer to H10W 72/07236>
D	H01L 2224/8182	<administrative transfer to H10W 72/07236>
D	H01L 2224/81825	<administrative transfer to H10W 72/07236>
D	H01L 2224/8183	<administrative transfer to H10W 72/07236>
D	H01L 2224/8184	<administrative transfer to H10W 72/072>
D	H01L 2224/8185	<administrative transfer to H10W 72/07237>
D	H01L 2224/81855	<administrative transfer to H10W 72/07237>
D	H01L 2224/81856	<administrative transfer to H10W 72/07237>
D	H01L 2224/81859	<administrative transfer to H10W 72/07237>
D	H01L 2224/81862	<administrative transfer to H10W 72/07237>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/81865	<administrative transfer to H10W 72/07237>
D	H01L 2224/81868	<administrative transfer to H10W 72/07237>
D	H01L 2224/81871	<administrative transfer to H10W 72/07237>
D	H01L 2224/81874	<administrative transfer to H10W 72/07237>
D	H01L 2224/81877	<administrative transfer to H10W 72/07237>
D	H01L 2224/8188	<administrative transfer to H10W 72/07237>
D	H01L 2224/81885	<administrative transfer to H10W 72/07237>
D	H01L 2224/8189	<administrative transfer to H10W 72/07231>
D	H01L 2224/81893	<administrative transfer to H10W 72/07231>
D	H01L 2224/81894	<administrative transfer to H10W 80/301>
D	H01L 2224/81895	<administrative transfer to H10W 80/314>
D	H01L 2224/81896	<administrative transfer to H10W 80/327>
D	H01L 2224/81897	<administrative transfer to H10W 72/07231>
D	H01L 2224/81898	<administrative transfer to H10W 72/07231>
D	H01L 2224/81899	<administrative transfer to H10W 72/07231>
D	H01L 2224/819	<administrative transfer to H10W 72/261>
D	H01L 2224/81901	<administrative transfer to H10W 72/261>
D	H01L 2224/81902	<administrative transfer to H10W 72/261>
D	H01L 2224/81903	<administrative transfer to H10W 72/261>
D	H01L 2224/81904	<administrative transfer to H10W 72/261>
D	H01L 2224/81905	<administrative transfer to H10W 72/07231>
D	H01L 2224/81906	<administrative transfer to H10W 72/07231>
D	H01L 2224/81907	<administrative transfer to H10W 72/07231>
D	H01L 2224/81908	<administrative transfer to H10W 72/07231>
D	H01L 2224/81909	<administrative transfer to H10W 72/012 and H10W 72/072 simultaneously>
D	H01L 2224/8191	<administrative transfer to H10W 72/01271 and H10W 72/072 simultaneously>
D	H01L 2224/81911	<administrative transfer to H10W 72/01271 and H10W 72/072 simultaneously>
D	H01L 2224/81912	<administrative transfer to H10W 72/01271 and H10W 72/072 simultaneously>
D	H01L 2224/81913	<administrative transfer to H10W 72/01271 and H10W 72/072 simultaneously>
D	H01L 2224/81914	<administrative transfer to H10W 72/01271 and H10W 72/072 simultaneously>
D	H01L 2224/81919	<administrative transfer to H10W 72/01271 and H10W 72/072 simultaneously>
D	H01L 2224/8192	<administrative transfer to H10W 72/01215 and H10W 72/072 simultaneously>
D	H01L 2224/8193	<administrative transfer to H10W 72/01251 and H10W 72/072 simultaneously>
D	H01L 2224/81931	<administrative transfer to H10W 72/01253 and H10W 72/072 simultaneously>
D	H01L 2224/81935	<administrative transfer to H10W 72/01257 and H10W 72/072 simultaneously>
D	H01L 2224/81937	<administrative transfer to H10W 72/01251 and H10W 72/072 simultaneously>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/81939	<administrative transfer to H10W 72/01251 and H10W 72/072 simultaneously>
D	H01L 2224/81941	<administrative transfer to H10W 72/01251 and H10W 72/072 simultaneously>
D	H01L 2224/81943	<administrative transfer to H10W 72/01251 and H10W 72/072 simultaneously>
D	H01L 2224/81945	<administrative transfer to H10W 72/01251 and H10W 72/072 simultaneously>
D	H01L 2224/81947	<administrative transfer to H10W 72/01251 and H10W 72/072 simultaneously>
D	H01L 2224/81948	<administrative transfer to H10W 72/012 and H10W 72/072 simultaneously>
D	H01L 2224/81951	<administrative transfer to H10W 72/01208 and H10W 72/072 simultaneously>
D	H01L 2224/81986	<administrative transfer to H10W 72/072>
D	H01L 2224/82	<administrative transfer to H10W 70/093>
D	H01L 2224/82001	<administrative transfer to H10W 70/093>
D	H01L 2224/82002	<administrative transfer to H10W 70/093>
D	H01L 2224/82005	<administrative transfer to H10W 70/093>
D	H01L 2224/82007	<administrative transfer to H10W 70/093>
D	H01L 2224/82009	<administrative transfer to H10W 70/093>
D	H01L 2224/8201	<administrative transfer to H10W 70/093>
D	H01L 2224/8203	<administrative transfer to H10W 70/093>
D	H01L 2224/82031	<administrative transfer to H10W 70/093>
D	H01L 2224/82035	<administrative transfer to H10W 70/093>
D	H01L 2224/82039	<administrative transfer to H10W 70/093>
D	H01L 2224/82045	<administrative transfer to H10W 70/093>
D	H01L 2224/82047	<administrative transfer to H10W 70/093>
D	H01L 2224/82048	<administrative transfer to H10W 70/093>
D	H01L 2224/82051	<administrative transfer to H10W 70/093>
D	H01L 2224/82053	<administrative transfer to H10W 70/093>
D	H01L 2224/82054	<administrative transfer to H10W 70/093>
D	H01L 2224/82085	<administrative transfer to H10W 70/093>
D	H01L 2224/8209	<administrative transfer to H10W 70/093>
D	H01L 2224/82091	<administrative transfer to H10W 70/093>
D	H01L 2224/82095	<administrative transfer to H10W 70/093>
D	H01L 2224/82096	<administrative transfer to H10W 70/093>
D	H01L 2224/82097	<administrative transfer to H10W 70/093>
D	H01L 2224/82098	<administrative transfer to H10W 70/093>
D	H01L 2224/82099	<administrative transfer to H10W 70/093>
D	H01L 2224/821	<administrative transfer to H10W 70/093>
D	H01L 2224/82101	<administrative transfer to H10W 70/093>
D	H01L 2224/82102	<administrative transfer to H10W 70/093>
D	H01L 2224/82103	<administrative transfer to H10W 70/093>
D	H01L 2224/82104	<administrative transfer to H10W 70/093>
D	H01L 2224/82105	<administrative transfer to H10W 70/093>
D	H01L 2224/82106	<administrative transfer to H10W 70/093>
D	H01L 2224/82108	<administrative transfer to H10W 70/093>
D	H01L 2224/8211	<administrative transfer to H10W 70/093>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/8212	<administrative transfer to H10W 70/093>
D	H01L 2224/82121	<administrative transfer to H10W 70/093>
D	H01L 2224/82122	<administrative transfer to H10W 70/093>
D	H01L 2224/8213	<administrative transfer to H10W 70/093>
D	H01L 2224/82132	<administrative transfer to H10W 70/093>
D	H01L 2224/82136	<administrative transfer to H10W 70/093>
D	H01L 2224/82138	<administrative transfer to H10W 70/093>
D	H01L 2224/82143	<administrative transfer to H10W 70/093>
D	H01L 2224/82148	<administrative transfer to H10W 70/093>
D	H01L 2224/82149	<administrative transfer to H10W 70/093>
D	H01L 2224/8215	<administrative transfer to H10W 70/093>
D	H01L 2224/8216	<administrative transfer to H10W 70/093>
D	H01L 2224/82169	<administrative transfer to H10W 70/093>
D	H01L 2224/8217	<administrative transfer to H10W 70/093>
D	H01L 2224/8218	<administrative transfer to H10W 70/093>
D	H01L 2224/82181	<administrative transfer to H10W 70/093>
D	H01L 2224/82186	<administrative transfer to H10W 70/093>
D	H01L 2224/82191	<administrative transfer to H10W 70/093>
D	H01L 2224/822	<administrative transfer to H10W 70/093>
D	H01L 2224/82201	<administrative transfer to H10W 70/093>
D	H01L 2224/82203	<administrative transfer to H10W 70/093>
D	H01L 2224/82205	<administrative transfer to H10W 70/093>
D	H01L 2224/82207	<administrative transfer to H10W 70/093>
D	H01L 2224/8221	<administrative transfer to H10W 70/093>
D	H01L 2224/82212	<administrative transfer to H10W 70/093>
D	H01L 2224/82214	<administrative transfer to H10W 70/093>
D	H01L 2224/8223	<administrative transfer to H10W 70/093>
D	H01L 2224/82232	<administrative transfer to H10W 70/093>
D	H01L 2224/82234	<administrative transfer to H10W 70/093>
D	H01L 2224/82236	<administrative transfer to H10W 70/093>
D	H01L 2224/82237	<administrative transfer to H10W 70/093>
D	H01L 2224/82238	<administrative transfer to H10W 70/093>
D	H01L 2224/8234	<administrative transfer to H10W 70/093>
D	H01L 2224/82345	<administrative transfer to H10W 70/093>
D	H01L 2224/82355	<administrative transfer to H10W 70/093>
D	H01L 2224/82359	<administrative transfer to H10W 70/093>
D	H01L 2224/8236	<administrative transfer to H10W 70/093>
D	H01L 2224/82365	<administrative transfer to H10W 70/093>
D	H01L 2224/82375	<administrative transfer to H10W 70/093>
D	H01L 2224/82379	<administrative transfer to H10W 70/093>
D	H01L 2224/8238	<administrative transfer to H10W 70/093>
D	H01L 2224/82385	<administrative transfer to H10W 70/093>
D	H01L 2224/82395	<administrative transfer to H10W 70/093>
D	H01L 2224/82399	<administrative transfer to H10W 70/093>
D	H01L 2224/828	<administrative transfer to H10W 70/093>
D	H01L 2224/82801	<administrative transfer to H10W 70/093>
D	H01L 2224/82805	<administrative transfer to H10W 70/093>
D	H01L 2224/8281	<administrative transfer to H10W 70/093>
D	H01L 2224/82815	<administrative transfer to H10W 70/093>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/8282	<administrative transfer to H10W 70/093>
D	H01L 2224/82825	<administrative transfer to H10W 70/093>
D	H01L 2224/8283	<administrative transfer to H10W 70/093>
D	H01L 2224/8284	<administrative transfer to H10W 70/093>
D	H01L 2224/8285	<administrative transfer to H10W 70/093>
D	H01L 2224/82855	<administrative transfer to H10W 70/093>
D	H01L 2224/82856	<administrative transfer to H10W 70/093>
D	H01L 2224/82859	<administrative transfer to H10W 70/093>
D	H01L 2224/82862	<administrative transfer to H10W 70/093>
D	H01L 2224/82865	<administrative transfer to H10W 70/093>
D	H01L 2224/82868	<administrative transfer to H10W 70/093>
D	H01L 2224/82871	<administrative transfer to H10W 70/093>
D	H01L 2224/82874	<administrative transfer to H10W 70/093>
D	H01L 2224/82877	<administrative transfer to H10W 70/093>
D	H01L 2224/8288	<administrative transfer to H10W 70/093>
D	H01L 2224/82885	<administrative transfer to H10W 70/093>
D	H01L 2224/8289	<administrative transfer to H10W 70/093>
D	H01L 2224/82893	<administrative transfer to H10W 70/093>
D	H01L 2224/82895	<administrative transfer to H10W 70/093>
D	H01L 2224/82896	<administrative transfer to H10W 70/093>
D	H01L 2224/82897	<administrative transfer to H10W 70/093>
D	H01L 2224/82899	<administrative transfer to H10W 70/093>
D	H01L 2224/829	<administrative transfer to H10W 70/093>
D	H01L 2224/82909	<administrative transfer to H10W 70/093>
D	H01L 2224/8291	<administrative transfer to H10W 70/093>
D	H01L 2224/8293	<administrative transfer to H10W 70/093>
D	H01L 2224/82931	<administrative transfer to H10W 70/093>
D	H01L 2224/82935	<administrative transfer to H10W 70/093>
D	H01L 2224/82939	<administrative transfer to H10W 70/093>
D	H01L 2224/82945	<administrative transfer to H10W 70/093>
D	H01L 2224/82947	<administrative transfer to H10W 70/093>
D	H01L 2224/82948	<administrative transfer to H10W 70/093>
D	H01L 2224/82951	<administrative transfer to H10W 70/093>
D	H01L 2224/82986	<administrative transfer to H10W 70/093>
D	H01L 2224/83	<administrative transfer to H10W 72/073>
D	H01L 2224/83001	<administrative transfer to H10W 72/07304>
D	H01L 2224/83002	<administrative transfer to H10W 72/07304>
D	H01L 2224/83005	<administrative transfer to H10W 72/07307>
D	H01L 2224/83007	<administrative transfer to H10W 72/07302>
D	H01L 2224/83009	<administrative transfer to H10W 72/07311>
D	H01L 2224/8301	<administrative transfer to H10W 72/07311 and H10W 72/01371 simultaneously>
D	H01L 2224/83011	<administrative transfer to H10W 72/07311 and H10W 72/01371 simultaneously>
D	H01L 2224/83012	<administrative transfer to H10W 72/07311 and H10W 72/01371 simultaneously>
D	H01L 2224/83013	<administrative transfer to H10W 72/07311 and H10W 72/01371 simultaneously>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/83014	<administrative transfer to H10W 72/07311 and H10W 72/01371 simultaneously>
D	H01L 2224/83019	<administrative transfer to H10W 72/07311 and H10W 72/01371 simultaneously>
D	H01L 2224/8302	<administrative transfer to H10W 72/07311 and H10W 72/01315 simultaneously>
D	H01L 2224/83022	<administrative transfer to H10W 72/07311 and H10W 72/01371 simultaneously>
D	H01L 2224/83024	<administrative transfer to H10W 72/07311 and H10W 72/013 simultaneously>
D	H01L 2224/83026	<administrative transfer to H10W 72/07311 and H10W 72/013 simultaneously>
D	H01L 2224/8303	<administrative transfer to H10W 72/07311 and H10W 72/01351 simultaneously>
D	H01L 2224/83031	<administrative transfer to H10W 72/07311 and H10W 72/01353 simultaneously>
D	H01L 2224/83035	<administrative transfer to H10W 72/07311 and H10W 72/01357 simultaneously>
D	H01L 2224/83037	<administrative transfer to H10W 72/07311 and H10W 72/01357 simultaneously>
D	H01L 2224/83039	<administrative transfer to H10W 72/07311 and H10W 72/01357 simultaneously>
D	H01L 2224/83041	<administrative transfer to H10W 72/07311 and H10W 72/01357 simultaneously>
D	H01L 2224/83047	<administrative transfer to H10W 72/07311 and H10W 72/01351 simultaneously>
D	H01L 2224/83048	<administrative transfer to H10W 72/07311 and H10W 72/01365 simultaneously>
D	H01L 2224/83051	<administrative transfer to H10W 72/07311>
D	H01L 2224/83052	<administrative transfer to H10W 72/073>
D	H01L 2224/83053	<administrative transfer to H10W 72/07341>
D	H01L 2224/83054	<administrative transfer to H10W 72/07341>
D	H01L 2224/83055	<administrative transfer to H10W 72/07341>
D	H01L 2224/83065	<administrative transfer to H10W 72/07341>
D	H01L 2224/83075	<administrative transfer to H10W 72/07341>
D	H01L 2224/83085	<administrative transfer to H10W 72/07341>
D	H01L 2224/8309	<administrative transfer to H10W 72/07341>
D	H01L 2224/83091	<administrative transfer to H10W 72/07341>
D	H01L 2224/83092	<administrative transfer to H10W 72/07341>
D	H01L 2224/83093	<administrative transfer to H10W 72/07341>
D	H01L 2224/83095	<administrative transfer to H10W 72/07341>
D	H01L 2224/83096	<administrative transfer to H10W 72/07341>
D	H01L 2224/83097	<administrative transfer to H10W 72/07341>
D	H01L 2224/83098	<administrative transfer to H10W 72/07341>
D	H01L 2224/83099	<administrative transfer to H10W 72/07341>
D	H01L 2224/831	<administrative transfer to H10W 72/073>
D	H01L 2224/83101	<administrative transfer to H10W 72/073>
D	H01L 2224/83102	<administrative transfer to H10W 72/073>
D	H01L 2224/83104	<administrative transfer to H10W 72/073>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/8311	<administrative transfer to H10W 72/073>
D	H01L 2224/8312	<administrative transfer to H10W 72/07321>
D	H01L 2224/83121	<administrative transfer to H10W 72/07323>
D	H01L 2224/83122	<administrative transfer to H10W 72/07323>
D	H01L 2224/83123	<administrative transfer to H10W 72/07323>
D	H01L 2224/83125	<administrative transfer to H10W 72/07323>
D	H01L 2224/83127	<administrative transfer to H10W 72/07323>
D	H01L 2224/83129	<administrative transfer to H10W 72/07323>
D	H01L 2224/8313	<administrative transfer to H10W 72/07323>
D	H01L 2224/83132	<administrative transfer to H10W 72/07323>
D	H01L 2224/83136	<administrative transfer to H10W 72/07327>
D	H01L 2224/83138	<administrative transfer to H10W 72/07327>
D	H01L 2224/83139	<administrative transfer to H10W 72/07327>
D	H01L 2224/8314	<administrative transfer to H10W 72/07327>
D	H01L 2224/83141	<administrative transfer to H10W 72/07327>
D	H01L 2224/83143	<administrative transfer to H10W 72/07321>
D	H01L 2224/83148	<administrative transfer to H10W 72/073>
D	H01L 2224/83149	<administrative transfer to H10W 72/073>
D	H01L 2224/8315	<administrative transfer to H10W 72/073>
D	H01L 2224/8316	<administrative transfer to H10W 72/073>
D	H01L 2224/83169	<administrative transfer to H10W 72/073>
D	H01L 2224/8317	<administrative transfer to H10W 72/073>
D	H01L 2224/8318	<administrative transfer to H10W 72/073>
D	H01L 2224/8319	<administrative transfer to H10W 72/073>
D	H01L 2224/83191	<administrative transfer to H10W 72/073>
D	H01L 2224/83192	<administrative transfer to H10W 72/073>
D	H01L 2224/83193	<administrative transfer to H10W 72/073>
D	H01L 2224/83194	<administrative transfer to H10W 72/073>
D	H01L 2224/832	<administrative transfer to H10W 72/07331>
D	H01L 2224/83201	<administrative transfer to H10W 72/07332>
D	H01L 2224/83203	<administrative transfer to H10W 72/07332>
D	H01L 2224/83204	<administrative transfer to H10W 72/07332>
D	H01L 2224/83205	<administrative transfer to H10W 72/07333>
D	H01L 2224/83206	<administrative transfer to H10W 72/07333>
D	H01L 2224/83207	<administrative transfer to H10W 72/07333>
D	H01L 2224/83208	<administrative transfer to H10W 72/07331>
D	H01L 2224/83209	<administrative transfer to H10W 72/07331>
D	H01L 2224/8321	<administrative transfer to H10W 72/07334>
D	H01L 2224/83211	<administrative transfer to H10W 72/07334>
D	H01L 2224/8322	<administrative transfer to H10W 72/07335>
D	H01L 2224/83222	<administrative transfer to H10W 72/07335>
D	H01L 2224/83224	<administrative transfer to H10W 72/07335>
D	H01L 2224/8323	<administrative transfer to H10W 72/07335>
D	H01L 2224/83232	<administrative transfer to H10W 72/07331>
D	H01L 2224/83234	<administrative transfer to H10W 72/07331>
D	H01L 2224/83236	<administrative transfer to H10W 72/07331>
D	H01L 2224/83237	<administrative transfer to H10W 72/07331>
D	H01L 2224/83238	<administrative transfer to H10W 72/07331>
D	H01L 2224/8334	<administrative transfer to H10W 72/073>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/83345	<administrative transfer to H10W 72/073 and H10W 72/331 simultaneously>
D	H01L 2224/83355	<administrative transfer to H10W 72/073 and H10W 72/322 simultaneously>
D	H01L 2224/83359	<administrative transfer to H10W 72/073 and H10W 72/351 simultaneously>
D	H01L 2224/8336	<administrative transfer to H10W 72/90>
D	H01L 2224/83365	<administrative transfer to H10W 72/931>
D	H01L 2224/83375	<administrative transfer to H10W 72/923>
D	H01L 2224/83379	<administrative transfer to H10W 72/951>
D	H01L 2224/8338	<administrative transfer to H10W 72/90>
D	H01L 2224/83385	<administrative transfer to H10W 72/931>
D	H01L 2224/83395	<administrative transfer to H10W 72/923>
D	H01L 2224/83399	<administrative transfer to H10W 72/951>
D	H01L 2224/834	<administrative transfer to H10W 72/952>
D	H01L 2224/83401	<administrative transfer to H10W 72/952>
D	H01L 2224/83405	<administrative transfer to H10W 72/952>
D	H01L 2224/83409	<administrative transfer to H10W 72/952>
D	H01L 2224/83411	<administrative transfer to H10W 72/952>
D	H01L 2224/83413	<administrative transfer to H10W 72/952>
D	H01L 2224/83414	<administrative transfer to H10W 72/952>
D	H01L 2224/83416	<administrative transfer to H10W 72/952>
D	H01L 2224/83417	<administrative transfer to H10W 72/952>
D	H01L 2224/83418	<administrative transfer to H10W 72/952>
D	H01L 2224/8342	<administrative transfer to H10W 72/952>
D	H01L 2224/83423	<administrative transfer to H10W 72/952>
D	H01L 2224/83424	<administrative transfer to H10W 72/952>
D	H01L 2224/83438	<administrative transfer to H10W 72/952>
D	H01L 2224/83439	<administrative transfer to H10W 72/952>
D	H01L 2224/83444	<administrative transfer to H10W 72/952>
D	H01L 2224/83447	<administrative transfer to H10W 72/952>
D	H01L 2224/83449	<administrative transfer to H10W 72/952>
D	H01L 2224/83455	<administrative transfer to H10W 72/952>
D	H01L 2224/83457	<administrative transfer to H10W 72/952>
D	H01L 2224/8346	<administrative transfer to H10W 72/952>
D	H01L 2224/83463	<administrative transfer to H10W 72/952>
D	H01L 2224/83464	<administrative transfer to H10W 72/952>
D	H01L 2224/83466	<administrative transfer to H10W 72/952>
D	H01L 2224/83469	<administrative transfer to H10W 72/952>
D	H01L 2224/8347	<administrative transfer to H10W 72/952>
D	H01L 2224/83471	<administrative transfer to H10W 72/952>
D	H01L 2224/83472	<administrative transfer to H10W 72/952>
D	H01L 2224/83473	<administrative transfer to H10W 72/952>
D	H01L 2224/83476	<administrative transfer to H10W 72/952>
D	H01L 2224/83478	<administrative transfer to H10W 72/952>
D	H01L 2224/83479	<administrative transfer to H10W 72/952>
D	H01L 2224/8348	<administrative transfer to H10W 72/952>
D	H01L 2224/83481	<administrative transfer to H10W 72/952>
D	H01L 2224/83483	<administrative transfer to H10W 72/952>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/83484	<administrative transfer to H10W 72/952>
D	H01L 2224/83486	<administrative transfer to H10W 72/953>
D	H01L 2224/83487	<administrative transfer to H10W 72/953>
D	H01L 2224/83488	<administrative transfer to H10W 72/953>
D	H01L 2224/8349	<administrative transfer to H10W 72/953>
D	H01L 2224/83491	<administrative transfer to H10W 72/953>
D	H01L 2224/83493	<administrative transfer to H10W 72/953>
D	H01L 2224/83494	<administrative transfer to H10W 72/953>
D	H01L 2224/83495	<administrative transfer to H10W 72/953>
D	H01L 2224/83498	<administrative transfer to H10W 72/925 and H10W 72/951 simultaneously>
D	H01L 2224/83499	<administrative transfer to H10W 72/925 and H10W 72/951 simultaneously>
D	H01L 2224/835	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/83501	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/83505	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/83509	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/83511	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/83513	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/83514	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/83516	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/83517	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/83518	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/8352	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/83523	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/83524	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/83538	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/83539	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/83544	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/83547	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/83549	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/83555	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/83557	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/8356	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/83563	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/83564	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/83566	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/83569	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/8357	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/83571	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/83572	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/83573	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/83576	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/83578	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/83579	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/8358	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/83581	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/83583	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/83584	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/83586	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>
D	H01L 2224/83587	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>
D	H01L 2224/83588	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>
D	H01L 2224/8359	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>
D	H01L 2224/83591	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>
D	H01L 2224/83593	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>
D	H01L 2224/83594	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/83595	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>
D	H01L 2224/83598	<administrative transfer to H10W 72/925 and H10W 72/951 simultaneously>
D	H01L 2224/83599	<administrative transfer to H10W 72/925 and H10W 72/951 simultaneously>
D	H01L 2224/836	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/83601	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/83605	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/83609	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/83611	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/83613	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/83614	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/83616	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/83617	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/83618	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/8362	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/83623	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/83624	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/83638	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/83639	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/83644	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/83647	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/83649	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/83655	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/83657	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/8366	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/83663	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/83664	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/83666	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/83669	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/8367	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/83671	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/83672	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/83673	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/83676	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/83678	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/83679	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/8368	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/83681	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/83683	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/83684	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/83686	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>
D	H01L 2224/83687	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>
D	H01L 2224/83688	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>
D	H01L 2224/8369	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>
D	H01L 2224/83691	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>
D	H01L 2224/83693	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>
D	H01L 2224/83694	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>
D	H01L 2224/83695	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>
D	H01L 2224/83698	<administrative transfer to H10W 72/925 and H10W 72/951 simultaneously>
D	H01L 2224/83699	<administrative transfer to H10W 72/925 and H10W 72/951 simultaneously>
D	H01L 2224/837	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/83701	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/83705	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/83709	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/83711	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/83713	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/83714	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/83716	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/83717	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/83718	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/8372	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/83723	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/83724	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/83738	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/83739	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/83744	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/83747	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/83749	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/83755	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/83757	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/8376	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/83763	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/83764	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/83766	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/83769	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/8377	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>

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Type*	<u>From CPC Symbol (existing)</u>	<u>To CPC Symbol(s)</u>
D	H01L 2224/83771	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/83772	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/83773	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/83776	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/83778	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/83779	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/8378	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/83781	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/83783	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/83784	<administrative transfer to H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/83786	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>
D	H01L 2224/83787	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>
D	H01L 2224/83788	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>
D	H01L 2224/8379	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>
D	H01L 2224/83791	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>
D	H01L 2224/83793	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>
D	H01L 2224/83794	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>
D	H01L 2224/83795	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>
D	H01L 2224/83798	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>
D	H01L 2224/83799	<administrative transfer to H10W 72/925 and H10W 72/953 simultaneously>
D	H01L 2224/838	<administrative transfer to H10W 72/07331>
D	H01L 2224/83801	<administrative transfer to H10W 72/07336>
D	H01L 2224/83805	<administrative transfer to H10W 72/07336>
D	H01L 2224/8381	<administrative transfer to H10W 72/07336>
D	H01L 2224/83815	<administrative transfer to H10W 72/07336>
D	H01L 2224/8382	<administrative transfer to H10W 72/07336>
D	H01L 2224/83825	<administrative transfer to H10W 72/07336>
D	H01L 2224/8383	<administrative transfer to H10W 72/07336>
D	H01L 2224/8384	<administrative transfer to H10W 72/07331>
D	H01L 2224/8385	<administrative transfer to H10W 72/07337>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/83851	<administrative transfer to H10W 72/074>
D	H01L 2224/83855	<administrative transfer to H10W 72/07338>
D	H01L 2224/83856	<administrative transfer to H10W 72/07338>
D	H01L 2224/83859	<administrative transfer to H10W 72/07338>
D	H01L 2224/83862	<administrative transfer to H10W 72/07338>
D	H01L 2224/83865	<administrative transfer to H10W 72/07338>
D	H01L 2224/83868	<administrative transfer to H10W 72/07338>
D	H01L 2224/83871	<administrative transfer to H10W 72/07338>
D	H01L 2224/83874	<administrative transfer to H10W 72/07338>
D	H01L 2224/83877	<administrative transfer to H10W 72/07338>
D	H01L 2224/8388	<administrative transfer to H10W 72/07339>
D	H01L 2224/83885	<administrative transfer to H10W 72/07331>
D	H01L 2224/83886	<administrative transfer to H10W 72/07331>
D	H01L 2224/83887	<administrative transfer to H10W 72/07331>
D	H01L 2224/83888	<administrative transfer to H10W 72/07331>
D	H01L 2224/83889	<administrative transfer to H10W 72/07331>
D	H01L 2224/8389	<administrative transfer to H10W 72/07331>
D	H01L 2224/83893	<administrative transfer to H10W 72/07331>
D	H01L 2224/83894	<administrative transfer to H10W 72/07331>
D	H01L 2224/83895	<administrative transfer to H10W 72/07331>
D	H01L 2224/83896	<administrative transfer to H10W 72/07331>
D	H01L 2224/83897	<administrative transfer to H10W 72/07331>
D	H01L 2224/83898	<administrative transfer to H10W 72/07331>
D	H01L 2224/83899	<administrative transfer to H10W 72/07331>
D	H01L 2224/839	<administrative transfer to H10W 72/07331>
D	H01L 2224/83901	<administrative transfer to H10W 72/07331>
D	H01L 2224/83902	<administrative transfer to H10W 72/07331>
D	H01L 2224/83903	<administrative transfer to H10W 72/07331>
D	H01L 2224/83904	<administrative transfer to H10W 72/07331>
D	H01L 2224/83905	<administrative transfer to H10W 72/07331>
D	H01L 2224/83906	<administrative transfer to H10W 72/07331>
D	H01L 2224/83907	<administrative transfer to H10W 72/07331>
D	H01L 2224/83908	<administrative transfer to H10W 72/07331>
D	H01L 2224/83909	<administrative transfer to H10W 72/07331 and H10W 72/013 simultaneously>
D	H01L 2224/8391	<administrative transfer to H10W 72/07331 and H10W 72/01371 simultaneously>
D	H01L 2224/83911	<administrative transfer to H10W 72/07331 and H10W 72/01371 simultaneously>
D	H01L 2224/83912	<administrative transfer to H10W 72/07331 and H10W 72/01371 simultaneously>
D	H01L 2224/83913	<administrative transfer to H10W 72/07331 and H10W 72/01371 simultaneously>
D	H01L 2224/83914	<administrative transfer to H10W 72/07331 and H10W 72/01371 simultaneously>
D	H01L 2224/83919	<administrative transfer to H10W 72/07331 and H10W 72/01371 simultaneously>
D	H01L 2224/8392	<administrative transfer to H10W 72/07331 and H10W 72/01315 simultaneously>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/8393	<administrative transfer to H10W 72/07331 and H10W 72/01351 simultaneously>
D	H01L 2224/83931	<administrative transfer to H10W 72/07331 and H10W 72/01353 simultaneously>
D	H01L 2224/83935	<administrative transfer to H10W 72/07331 and H10W 72/01357 simultaneously>
D	H01L 2224/83937	<administrative transfer to H10W 72/07331 and H10W 72/01357 simultaneously>
D	H01L 2224/83939	<administrative transfer to H10W 72/07331 and H10W 72/01357 simultaneously>
D	H01L 2224/83941	<administrative transfer to H10W 72/07331 and H10W 72/01357 simultaneously>
D	H01L 2224/83943	<administrative transfer to H10W 72/07331 and H10W 72/01357 simultaneously>
D	H01L 2224/83945	<administrative transfer to H10W 72/07331 and H10W 72/01357 simultaneously>
D	H01L 2224/83947	<administrative transfer to H10W 72/07331 and H10W 72/01351 simultaneously>
D	H01L 2224/83948	<administrative transfer to H10W 72/07331 and H10W 72/01365 simultaneously>
D	H01L 2224/83951	<administrative transfer to H10W 72/07331>
D	H01L 2224/83986	<administrative transfer to H10W 72/07331>
D	H01L 2224/84	<administrative transfer to H10W 72/076>
D	H01L 2224/84001	<administrative transfer to H10W 72/07604>
D	H01L 2224/84002	<administrative transfer to H10W 72/07604>
D	H01L 2224/84005	<administrative transfer to H10W 72/07607>
D	H01L 2224/84007	<administrative transfer to H10W 72/07602>
D	H01L 2224/84009	<administrative transfer to H10W 72/07611 and H10W 72/016 simultaneously>
D	H01L 2224/8401	<administrative transfer to H10W 72/07611 and H10W 72/01671 simultaneously>
D	H01L 2224/84011	<administrative transfer to H10W 72/07611 and H10W 72/01671 simultaneously>
D	H01L 2224/84012	<administrative transfer to H10W 72/07611 and H10W 72/01671 simultaneously>
D	H01L 2224/84013	<administrative transfer to H10W 72/07611 and H10W 72/01671 simultaneously>
D	H01L 2224/84014	<administrative transfer to H10W 72/07611 and H10W 72/01671 simultaneously>
D	H01L 2224/84019	<administrative transfer to H10W 72/07611 and H10W 72/01671 simultaneously>
D	H01L 2224/8402	<administrative transfer to H10W 72/07611 and H10W 72/01615 simultaneously>
D	H01L 2224/8403	<administrative transfer to H10W 72/07611 and H10W 72/01651 simultaneously>
D	H01L 2224/84031	<administrative transfer to H10W 72/07611 and H10W 72/01653 simultaneously>
D	H01L 2224/84035	<administrative transfer to H10W 72/07611 and H10W 72/01651 simultaneously>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/84037	<administrative transfer to H10W 72/07611 and H10W 72/01651 simultaneously>
D	H01L 2224/84039	<administrative transfer to H10W 72/07611 and H10W 72/01651 simultaneously>
D	H01L 2224/84041	<administrative transfer to H10W 72/07611 and H10W 72/01651 simultaneously>
D	H01L 2224/84043	<administrative transfer to H10W 72/07611 and H10W 72/01651 simultaneously>
D	H01L 2224/84045	<administrative transfer to H10W 72/07611 and H10W 72/01651 simultaneously>
D	H01L 2224/84047	<administrative transfer to H10W 72/07611 and H10W 72/01651 simultaneously>
D	H01L 2224/84048	<administrative transfer to H10W 72/07611 and H10W 72/016 simultaneously>
D	H01L 2224/84051	<administrative transfer to H10W 72/07611 and H10W 72/016 simultaneously>
D	H01L 2224/84053	<administrative transfer to H10W 72/07641>
D	H01L 2224/84054	<administrative transfer to H10W 72/07641>
D	H01L 2224/84055	<administrative transfer to H10W 72/07641>
D	H01L 2224/84065	<administrative transfer to H10W 72/07641>
D	H01L 2224/84075	<administrative transfer to H10W 72/07641>
D	H01L 2224/84085	<administrative transfer to H10W 72/07641>
D	H01L 2224/8409	<administrative transfer to H10W 72/07641>
D	H01L 2224/84091	<administrative transfer to H10W 72/07641>
D	H01L 2224/84092	<administrative transfer to H10W 72/07641>
D	H01L 2224/84093	<administrative transfer to H10W 72/07641>
D	H01L 2224/84095	<administrative transfer to H10W 72/07641>
D	H01L 2224/84096	<administrative transfer to H10W 72/07641>
D	H01L 2224/84097	<administrative transfer to H10W 72/07641>
D	H01L 2224/84098	<administrative transfer to H10W 72/07641>
D	H01L 2224/84099	<administrative transfer to H10W 72/07641>
D	H01L 2224/841	<administrative transfer to H10W 72/076>
D	H01L 2224/8411	<administrative transfer to H10W 72/076>
D	H01L 2224/8412	<administrative transfer to H10W 72/07621>
D	H01L 2224/84121	<administrative transfer to H10W 72/07623>
D	H01L 2224/84122	<administrative transfer to H10W 72/07623>
D	H01L 2224/84123	<administrative transfer to H10W 72/07623>
D	H01L 2224/84125	<administrative transfer to H10W 72/07623>
D	H01L 2224/84127	<administrative transfer to H10W 72/07623>
D	H01L 2224/84129	<administrative transfer to H10W 72/07623>
D	H01L 2224/8413	<administrative transfer to H10W 72/07623>
D	H01L 2224/84132	<administrative transfer to H10W 72/07623>
D	H01L 2224/84136	<administrative transfer to H10W 72/07627>
D	H01L 2224/84138	<administrative transfer to H10W 72/07627>
D	H01L 2224/84143	<administrative transfer to H10W 72/07621>
D	H01L 2224/84148	<administrative transfer to H10W 72/076>
D	H01L 2224/84149	<administrative transfer to H10W 72/076>
D	H01L 2224/8415	<administrative transfer to H10W 72/076>
D	H01L 2224/8416	<administrative transfer to H10W 72/076>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/84169	<administrative transfer to H10W 72/076>
D	H01L 2224/8417	<administrative transfer to H10W 72/076>
D	H01L 2224/8418	<administrative transfer to H10W 72/076>
D	H01L 2224/84181	<administrative transfer to H10W 72/076>
D	H01L 2224/84186	<administrative transfer to H10W 72/076>
D	H01L 2224/84191	<administrative transfer to H10W 72/076>
D	H01L 2224/84196	<administrative transfer to H10W 72/076>
D	H01L 2224/842	<administrative transfer to H10W 72/07631>
D	H01L 2224/84201	<administrative transfer to H10W 72/07632>
D	H01L 2224/84203	<administrative transfer to H10W 72/07632>
D	H01L 2224/84205	<administrative transfer to H10W 72/07633>
D	H01L 2224/84206	<administrative transfer to H10W 72/07633>
D	H01L 2224/84207	<administrative transfer to H10W 72/07633>
D	H01L 2224/8421	<administrative transfer to H10W 72/07635>
D	H01L 2224/84212	<administrative transfer to H10W 72/07635>
D	H01L 2224/84214	<administrative transfer to H10W 72/07635>
D	H01L 2224/8423	<administrative transfer to H10W 72/07635>
D	H01L 2224/84232	<administrative transfer to H10W 72/07631>
D	H01L 2224/84234	<administrative transfer to H10W 72/07631>
D	H01L 2224/84236	<administrative transfer to H10W 72/07631>
D	H01L 2224/84237	<administrative transfer to H10W 72/07631>
D	H01L 2224/84238	<administrative transfer to H10W 72/07631>
D	H01L 2224/8434	<administrative transfer to H10W 72/076>
D	H01L 2224/84345	<administrative transfer to H10W 72/076 and H10W 72/631 simultaneously>
D	H01L 2224/84355	<administrative transfer to H10W 72/076 and H10W 72/621 simultaneously>
D	H01L 2224/84359	<administrative transfer to H10W 72/076 and H10W 72/651 simultaneously>
D	H01L 2224/8436	<administrative transfer to H10W 72/076>
D	H01L 2224/84365	<administrative transfer to H10W 72/076 and H10W 72/931 simultaneously>
D	H01L 2224/84375	<administrative transfer to H10W 72/076 and H10W 72/923 simultaneously>
D	H01L 2224/84379	<administrative transfer to H10W 72/076 and H10W 72/951 simultaneously>
D	H01L 2224/8438	<administrative transfer to H10W 72/076>
D	H01L 2224/84385	<administrative transfer to H10W 72/076 and H10W 72/931 simultaneously>
D	H01L 2224/84395	<administrative transfer to H10W 72/076 and H10W 72/923 simultaneously>
D	H01L 2224/84399	<administrative transfer to H10W 72/076 and H10W 72/951 simultaneously>
D	H01L 2224/844	<administrative transfer to H10W 72/076 and H10W 72/952 simultaneously>
D	H01L 2224/84401	<administrative transfer to H10W 72/076 and H10W 72/952 simultaneously>
D	H01L 2224/84405	<administrative transfer to H10W 72/076 and H10W 72/952 simultaneously>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/84409	<administrative transfer to H10W 72/076 and H10W 72/952 simultaneously>
D	H01L 2224/84411	<administrative transfer to H10W 72/076 and H10W 72/952 simultaneously>
D	H01L 2224/84413	<administrative transfer to H10W 72/076 and H10W 72/952 simultaneously>
D	H01L 2224/84414	<administrative transfer to H10W 72/076 and H10W 72/952 simultaneously>
D	H01L 2224/84416	<administrative transfer to H10W 72/076 and H10W 72/952 simultaneously>
D	H01L 2224/84417	<administrative transfer to H10W 72/076 and H10W 72/952 simultaneously>
D	H01L 2224/84418	<administrative transfer to H10W 72/076 and H10W 72/952 simultaneously>
D	H01L 2224/8442	<administrative transfer to H10W 72/076 and H10W 72/952 simultaneously>
D	H01L 2224/84423	<administrative transfer to H10W 72/076 and H10W 72/952 simultaneously>
D	H01L 2224/84424	<administrative transfer to H10W 72/076 and H10W 72/952 simultaneously>
D	H01L 2224/84438	<administrative transfer to H10W 72/076 and H10W 72/952 simultaneously>
D	H01L 2224/84439	<administrative transfer to H10W 72/076 and H10W 72/952 simultaneously>
D	H01L 2224/84444	<administrative transfer to H10W 72/076 and H10W 72/952 simultaneously>
D	H01L 2224/84447	<administrative transfer to H10W 72/076 and H10W 72/952 simultaneously>
D	H01L 2224/84449	<administrative transfer to H10W 72/076 and H10W 72/952 simultaneously>
D	H01L 2224/84455	<administrative transfer to H10W 72/076 and H10W 72/952 simultaneously>
D	H01L 2224/84457	<administrative transfer to H10W 72/076 and H10W 72/952 simultaneously>
D	H01L 2224/8446	<administrative transfer to H10W 72/076 and H10W 72/952 simultaneously>
D	H01L 2224/84463	<administrative transfer to H10W 72/076 and H10W 72/952 simultaneously>
D	H01L 2224/84464	<administrative transfer to H10W 72/076 and H10W 72/952 simultaneously>
D	H01L 2224/84466	<administrative transfer to H10W 72/076 and H10W 72/952 simultaneously>
D	H01L 2224/84469	<administrative transfer to H10W 72/076 and H10W 72/952 simultaneously>
D	H01L 2224/8447	<administrative transfer to H10W 72/076 and H10W 72/952 simultaneously>
D	H01L 2224/84471	<administrative transfer to H10W 72/076 and H10W 72/952 simultaneously>
D	H01L 2224/84472	<administrative transfer to H10W 72/076 and H10W 72/952 simultaneously>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/84473	<administrative transfer to H10W 72/076 and H10W 72/952 simultaneously>
D	H01L 2224/84476	<administrative transfer to H10W 72/076 and H10W 72/952 simultaneously>
D	H01L 2224/84478	<administrative transfer to H10W 72/076 and H10W 72/952 simultaneously>
D	H01L 2224/84479	<administrative transfer to H10W 72/076 and H10W 72/952 simultaneously>
D	H01L 2224/8448	<administrative transfer to H10W 72/076 and H10W 72/952 simultaneously>
D	H01L 2224/84481	<administrative transfer to H10W 72/076 and H10W 72/952 simultaneously>
D	H01L 2224/84483	<administrative transfer to H10W 72/076 and H10W 72/952 simultaneously>
D	H01L 2224/84484	<administrative transfer to H10W 72/076 and H10W 72/952 simultaneously>
D	H01L 2224/84486	<administrative transfer to H10W 72/076 and H10W 72/953 simultaneously>
D	H01L 2224/84487	<administrative transfer to H10W 72/076 and H10W 72/953 simultaneously>
D	H01L 2224/84488	<administrative transfer to H10W 72/076 and H10W 72/953 simultaneously>
D	H01L 2224/8449	<administrative transfer to H10W 72/076 and H10W 72/953 simultaneously>
D	H01L 2224/84491	<administrative transfer to H10W 72/076 and H10W 72/953 simultaneously>
D	H01L 2224/84493	<administrative transfer to H10W 72/076 and H10W 72/953 simultaneously>
D	H01L 2224/84494	<administrative transfer to H10W 72/076 and H10W 72/953 simultaneously>
D	H01L 2224/84495	<administrative transfer to H10W 72/076 and H10W 72/953 simultaneously>
D	H01L 2224/84498	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/951 simultaneously>
D	H01L 2224/84499	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/951 simultaneously>
D	H01L 2224/845	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/84501	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/84505	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/84509	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/84511	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/84513	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/84514	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/84516	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/84517	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/84518	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/8452	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/84523	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/84524	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/84538	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/84539	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/84544	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/84547	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/84549	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/84555	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/84557	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/8456	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/84563	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/84564	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/84566	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/84569	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/8457	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/84571	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/84572	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/84573	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/84576	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/84578	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/84579	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/8458	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/84581	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/84583	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/84584	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/84586	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/953 simultaneously>
D	H01L 2224/84587	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/953 simultaneously>
D	H01L 2224/84588	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/953 simultaneously>
D	H01L 2224/8459	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/953 simultaneously>
D	H01L 2224/84591	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/953 simultaneously>
D	H01L 2224/84593	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/953 simultaneously>
D	H01L 2224/84594	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/953 simultaneously>
D	H01L 2224/84595	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/953 simultaneously>
D	H01L 2224/84598	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/951 simultaneously>
D	H01L 2224/84599	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/951 simultaneously>
D	H01L 2224/846	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/84601	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/84605	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/84609	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/84611	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/84613	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/84614	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/84616	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/84617	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/84618	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/8462	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/84623	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/84624	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/84638	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/84639	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/84644	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/84647	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/84649	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/84655	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/84657	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/8466	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/84663	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/84664	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/84666	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/84669	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/8467	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/84671	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/84672	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/84673	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/84676	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/84678	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/84679	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/8468	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/84681	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/84683	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/84684	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/84686	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/953 simultaneously>
D	H01L 2224/84687	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/953 simultaneously>
D	H01L 2224/84688	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/953 simultaneously>
D	H01L 2224/8469	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/953 simultaneously>
D	H01L 2224/84691	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/953 simultaneously>
D	H01L 2224/84693	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/953 simultaneously>
D	H01L 2224/84694	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/953 simultaneously>
D	H01L 2224/84695	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/953 simultaneously>
D	H01L 2224/84698	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/951 simultaneously>
D	H01L 2224/84699	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/951 simultaneously>
D	H01L 2224/847	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/84701	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/84705	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/84709	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/84711	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/84713	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/84714	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/84716	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/84717	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/84718	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/8472	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/84723	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/84724	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/84738	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/84739	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/84744	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/84747	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/84749	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/84755	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/84757	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/8476	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/84763	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/84764	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/84766	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/84769	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/8477	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/84771	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/84772	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/84773	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/84776	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/84778	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/84779	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/8478	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/84781	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/84783	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/84784	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/952 simultaneously>
D	H01L 2224/84786	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/953 simultaneously>
D	H01L 2224/84787	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/953 simultaneously>
D	H01L 2224/84788	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/953 simultaneously>
D	H01L 2224/8479	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/953 simultaneously>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/84791	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/953 simultaneously>
D	H01L 2224/84793	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/953 simultaneously>
D	H01L 2224/84794	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/953 simultaneously>
D	H01L 2224/84795	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/953 simultaneously>
D	H01L 2224/84798	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/951 simultaneously>
D	H01L 2224/84799	<administrative transfer to H10W 72/076, H10W 72/925 and H10W 72/951 simultaneously>
D	H01L 2224/848	<administrative transfer to H10W 72/07631>
D	H01L 2224/84801	<administrative transfer to H10W 72/07636>
D	H01L 2224/84805	<administrative transfer to H10W 72/07636 and H10W 72/07655 simultaneously>
D	H01L 2224/8481	<administrative transfer to H10W 72/07636 and H10W 72/6528 simultaneously>
D	H01L 2224/84815	<administrative transfer to H10W 72/07636>
D	H01L 2224/8482	<administrative transfer to H10W 72/07631>
D	H01L 2224/84825	<administrative transfer to H10W 72/07631>
D	H01L 2224/8483	<administrative transfer to H10W 72/07631>
D	H01L 2224/8484	<administrative transfer to H10W 72/07631>
D	H01L 2224/8485	<administrative transfer to H10W 72/07637>
D	H01L 2224/84855	<administrative transfer to H10W 72/07637>
D	H01L 2224/84856	<administrative transfer to H10W 72/07637>
D	H01L 2224/84859	<administrative transfer to H10W 72/07637>
D	H01L 2224/84862	<administrative transfer to H10W 72/07637>
D	H01L 2224/84865	<administrative transfer to H10W 72/07637>
D	H01L 2224/84868	<administrative transfer to H10W 72/07637>
D	H01L 2224/84871	<administrative transfer to H10W 72/07637>
D	H01L 2224/84874	<administrative transfer to H10W 72/07637>
D	H01L 2224/84877	<administrative transfer to H10W 72/07637>
D	H01L 2224/8488	<administrative transfer to H10W 72/07637>
D	H01L 2224/84885	<administrative transfer to H10W 72/07637>
D	H01L 2224/8489	<administrative transfer to H10W 72/07631>
D	H01L 2224/84893	<administrative transfer to H10W 72/07631>
D	H01L 2224/84895	<administrative transfer to H10W 72/07631>
D	H01L 2224/84897	<administrative transfer to H10W 72/07631>
D	H01L 2224/84898	<administrative transfer to H10W 72/07631>
D	H01L 2224/84899	<administrative transfer to H10W 72/07631>
D	H01L 2224/849	<administrative transfer to H10W 72/07631>
D	H01L 2224/84909	<administrative transfer to H10W 72/076 and H10W 72/016 simultaneously>
D	H01L 2224/8491	<administrative transfer to H10W 72/076 and H10W 72/01671 simultaneously>
D	H01L 2224/84911	<administrative transfer to H10W 72/076 and H10W 72/01671 simultaneously>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/84912	<administrative transfer to H10W 72/076 and H10W 72/01671 simultaneously>
D	H01L 2224/84913	<administrative transfer to H10W 72/076 and H10W 72/01671 simultaneously>
D	H01L 2224/84914	<administrative transfer to H10W 72/076 and H10W 72/01671 simultaneously>
D	H01L 2224/84919	<administrative transfer to H10W 72/076 and H10W 72/01671 simultaneously>
D	H01L 2224/8492	<administrative transfer to H10W 72/076 and H10W 72/01615 simultaneously>
D	H01L 2224/8493	<administrative transfer to H10W 72/076 and H10W 72/01651 simultaneously>
D	H01L 2224/84931	<administrative transfer to H10W 72/076 and H10W 72/01653 simultaneously>
D	H01L 2224/84935	<administrative transfer to H10W 72/076 and H10W 72/016 simultaneously>
D	H01L 2224/84937	<administrative transfer to H10W 72/076 and H10W 72/016 simultaneously>
D	H01L 2224/84939	<administrative transfer to H10W 72/076 and H10W 72/016 simultaneously>
D	H01L 2224/84941	<administrative transfer to H10W 72/076 and H10W 72/016 simultaneously>
D	H01L 2224/84943	<administrative transfer to H10W 72/076 and H10W 72/016 simultaneously>
D	H01L 2224/84945	<administrative transfer to H10W 72/076 and H10W 72/016 simultaneously>
D	H01L 2224/84947	<administrative transfer to H10W 72/076 and H10W 72/01661 simultaneously>
D	H01L 2224/84948	<administrative transfer to H10W 72/076 and H10W 72/016 simultaneously>
D	H01L 2224/84951	<administrative transfer to H10W 72/076 and H10W 72/016 simultaneously>
D	H01L 2224/84986	<administrative transfer to H10W 72/076>
D	H01L 2224/85	<administrative transfer to H10W 72/075>
D	H01L 2224/85001	<administrative transfer to H10W 72/07504>
D	H01L 2224/85002	<administrative transfer to H10W 72/07504>
D	H01L 2224/85005	<administrative transfer to H10W 72/07507>
D	H01L 2224/85007	<administrative transfer to H10W 72/07502>
D	H01L 2224/85009	<administrative transfer to H10W 72/07511 and H10W 72/015 simultaneously>
D	H01L 2224/8501	<administrative transfer to H10W 72/07511 and H10W 72/01571 simultaneously>
D	H01L 2224/85011	<administrative transfer to H10W 72/07511 and H10W 72/01571 simultaneously>
D	H01L 2224/85012	<administrative transfer to H10W 72/07511 and H10W 72/01571 simultaneously>
D	H01L 2224/85013	<administrative transfer to H10W 72/07511 and H10W 72/01571 simultaneously>
D	H01L 2224/85014	<administrative transfer to H10W 72/07511 and H10W 72/01571 simultaneously>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/85016	<administrative transfer to H10W 72/07511 and H10W 72/01571 simultaneously>
D	H01L 2224/85017	<administrative transfer to H10W 72/07511 and H10W 72/01571 simultaneously>
D	H01L 2224/85019	<administrative transfer to H10W 72/07511 and H10W 72/01571 simultaneously>
D	H01L 2224/8502	<administrative transfer to H10W 72/07511 and H10W 72/01515 simultaneously>
D	H01L 2224/8503	<administrative transfer to H10W 72/07511 and H10W 72/01551 simultaneously>
D	H01L 2224/85031	<administrative transfer to H10W 72/07511 and H10W 72/01553 simultaneously>
D	H01L 2224/85035	<administrative transfer to H10W 72/07511 and H10W 72/01551 simultaneously>
D	H01L 2224/85037	<administrative transfer to H10W 72/07511 and H10W 72/01551 simultaneously>
D	H01L 2224/85039	<administrative transfer to H10W 72/07511 and H10W 72/01551 simultaneously>
D	H01L 2224/85041	<administrative transfer to H10W 72/07511 and H10W 72/01551 simultaneously>
D	H01L 2224/85043	<administrative transfer to H10W 72/07511 and H10W 72/01551 simultaneously>
D	H01L 2224/85045	<administrative transfer to H10W 72/07511 and H10W 72/01551 simultaneously>
D	H01L 2224/85047	<administrative transfer to H10W 72/07511 and H10W 72/01551 simultaneously>
D	H01L 2224/85048	<administrative transfer to H10W 72/07511>
D	H01L 2224/85051	<administrative transfer to H10W 72/07511>
D	H01L 2224/85053	<administrative transfer to H10W 72/07541>
D	H01L 2224/85054	<administrative transfer to H10W 72/07541>
D	H01L 2224/85055	<administrative transfer to H10W 72/07541>
D	H01L 2224/85065	<administrative transfer to H10W 72/07541>
D	H01L 2224/85075	<administrative transfer to H10W 72/07541>
D	H01L 2224/85085	<administrative transfer to H10W 72/07541>
D	H01L 2224/8509	<administrative transfer to H10W 72/07541>
D	H01L 2224/85091	<administrative transfer to H10W 72/07541>
D	H01L 2224/85092	<administrative transfer to H10W 72/07541>
D	H01L 2224/85093	<administrative transfer to H10W 72/07541>
D	H01L 2224/85095	<administrative transfer to H10W 72/07541>
D	H01L 2224/85096	<administrative transfer to H10W 72/07541>
D	H01L 2224/85097	<administrative transfer to H10W 72/07541>
D	H01L 2224/85098	<administrative transfer to H10W 72/07541>
D	H01L 2224/85099	<administrative transfer to H10W 72/07541>
D	H01L 2224/851	<administrative transfer to H10W 72/07502>
D	H01L 2224/8511	<administrative transfer to H10W 72/07502>
D	H01L 2224/8512	<administrative transfer to H10W 72/07521>
D	H01L 2224/85121	<administrative transfer to H10W 72/07523>
D	H01L 2224/85122	<administrative transfer to H10W 72/07523>
D	H01L 2224/85123	<administrative transfer to H10W 72/07523>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/85125	<administrative transfer to H10W 72/07523>
D	H01L 2224/85127	<administrative transfer to H10W 72/07523>
D	H01L 2224/85129	<administrative transfer to H10W 72/07523>
D	H01L 2224/8513	<administrative transfer to H10W 72/07523>
D	H01L 2224/85132	<administrative transfer to H10W 72/07523>
D	H01L 2224/85136	<administrative transfer to H10W 72/07527>
D	H01L 2224/85138	<administrative transfer to H10W 72/07527>
D	H01L 2224/85143	<administrative transfer to H10W 72/07521>
D	H01L 2224/85148	<administrative transfer to H10W 72/07521>
D	H01L 2224/85149	<administrative transfer to H10W 72/07521>
D	H01L 2224/8515	<administrative transfer to H10W 72/07521>
D	H01L 2224/8516	<administrative transfer to H10W 72/07521>
D	H01L 2224/85169	<administrative transfer to H10W 72/07521>
D	H01L 2224/8517	<administrative transfer to H10W 72/07521>
D	H01L 2224/8518	<administrative transfer to H10W 72/07521>
D	H01L 2224/85181	<administrative transfer to H10W 72/07521>
D	H01L 2224/85186	<administrative transfer to H10W 72/07521>
D	H01L 2224/85191	<administrative transfer to H10W 72/07521>
D	H01L 2224/85196	<administrative transfer to H10W 72/07521>
D	H01L 2224/852	<administrative transfer to H10W 72/07531>
D	H01L 2224/85201	<administrative transfer to H10W 72/07532>
D	H01L 2224/85203	<administrative transfer to H10W 72/07532>
D	H01L 2224/85205	<administrative transfer to H10W 72/07533>
D	H01L 2224/85206	<administrative transfer to H10W 72/07533>
D	H01L 2224/85207	<administrative transfer to H10W 72/07533>
D	H01L 2224/8521	<administrative transfer to H10W 72/07535>
D	H01L 2224/85212	<administrative transfer to H10W 72/07535>
D	H01L 2224/85214	<administrative transfer to H10W 72/07535>
D	H01L 2224/8523	<administrative transfer to H10W 72/07535>
D	H01L 2224/85232	<administrative transfer to H10W 72/07531>
D	H01L 2224/85234	<administrative transfer to H10W 72/07531>
D	H01L 2224/85236	<administrative transfer to H10W 72/07531>
D	H01L 2224/85237	<administrative transfer to H10W 72/07531>
D	H01L 2224/85238	<administrative transfer to H10W 72/07531>
D	H01L 2224/8534	<administrative transfer to H10W 72/075>
D	H01L 2224/85345	<administrative transfer to H10W 72/075 and H10W 72/531 simultaneously>
D	H01L 2224/85355	<administrative transfer to H10W 72/075 and H10W 72/332 simultaneously>
D	H01L 2224/85359	<administrative transfer to H10W 72/075 and H10W 72/551 simultaneously>
D	H01L 2224/8536	<administrative transfer to H10W 72/075 and H10W 72/90 simultaneously>
D	H01L 2224/85365	<administrative transfer to H10W 72/075 and H10W 72/931 simultaneously>
D	H01L 2224/85375	<administrative transfer to H10W 72/075 and H10W 72/923 simultaneously>
D	H01L 2224/85379	<administrative transfer to H10W 72/075 and H10W 72/951 simultaneously>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/8538	<administrative transfer to H10W 72/075 and H10W 72/90 simultaneously>
D	H01L 2224/85385	<administrative transfer to H10W 72/075 and H10W 72/931 simultaneously>
D	H01L 2224/85395	<administrative transfer to H10W 72/075 and H10W 72/923 simultaneously>
D	H01L 2224/85399	<administrative transfer to H10W 72/075 and H10W 72/951 simultaneously>
D	H01L 2224/854	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85401	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85405	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85409	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85411	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85413	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85414	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85416	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85417	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85418	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/8542	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85423	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85424	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85438	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85439	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85444	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85447	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85449	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85455	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85457	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/8546	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/85463	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85464	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85466	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85469	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/8547	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85471	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85472	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85473	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85476	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85478	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85479	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/8548	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85481	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85483	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85484	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85486	<administrative transfer to H10W 72/075 and H10W 72/953 simultaneously>
D	H01L 2224/85487	<administrative transfer to H10W 72/075 and H10W 72/953 simultaneously>
D	H01L 2224/85488	<administrative transfer to H10W 72/075 and H10W 72/953 simultaneously>
D	H01L 2224/8549	<administrative transfer to H10W 72/075 and H10W 72/953 simultaneously>
D	H01L 2224/85491	<administrative transfer to H10W 72/075 and H10W 72/953 simultaneously>
D	H01L 2224/85493	<administrative transfer to H10W 72/075 and H10W 72/953 simultaneously>
D	H01L 2224/85494	<administrative transfer to H10W 72/075 and H10W 72/953 simultaneously>
D	H01L 2224/85495	<administrative transfer to H10W 72/075 and H10W 72/953 simultaneously>
D	H01L 2224/85498	<administrative transfer to H10W 72/075 and H10W 72/951 simultaneously>
D	H01L 2224/85499	<administrative transfer to H10W 72/075 and H10W 72/951 simultaneously>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/855	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85501	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85505	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85509	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85511	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85513	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85514	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85516	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85517	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85518	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/8552	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85523	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85524	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85538	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85539	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85544	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85547	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85549	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85555	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85557	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/8556	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85563	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85564	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85566	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85569	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/8557	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85571	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85572	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85573	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85576	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85578	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85579	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/8558	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85581	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85583	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85584	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85586	<administrative transfer to H10W 72/075 and H10W 72/953 simultaneously>
D	H01L 2224/85587	<administrative transfer to H10W 72/075 and H10W 72/953 simultaneously>
D	H01L 2224/85588	<administrative transfer to H10W 72/075 and H10W 72/953 simultaneously>
D	H01L 2224/8559	<administrative transfer to H10W 72/075 and H10W 72/953 simultaneously>
D	H01L 2224/85591	<administrative transfer to H10W 72/075 and H10W 72/953 simultaneously>
D	H01L 2224/85593	<administrative transfer to H10W 72/075 and H10W 72/953 simultaneously>
D	H01L 2224/85594	<administrative transfer to H10W 72/075 and H10W 72/953 simultaneously>
D	H01L 2224/85595	<administrative transfer to H10W 72/075 and H10W 72/953 simultaneously>
D	H01L 2224/85598	<administrative transfer to H10W 72/075 and H10W 72/951 simultaneously>
D	H01L 2224/85599	<administrative transfer to H10W 72/075 and H10W 72/951 simultaneously>
D	H01L 2224/856	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85601	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85605	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85609	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/85611	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85613	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85614	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85616	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85617	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85618	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/8562	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85623	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85624	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85638	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85639	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85644	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85647	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85649	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85655	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85657	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/8566	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85663	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85664	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85666	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85669	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/8567	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85671	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85672	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85673	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/85676	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85678	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85679	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/8568	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85681	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85683	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85684	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85686	<administrative transfer to H10W 72/075 and H10W 72/953 simultaneously>
D	H01L 2224/85687	<administrative transfer to H10W 72/075 and H10W 72/953 simultaneously>
D	H01L 2224/85688	<administrative transfer to H10W 72/075 and H10W 72/953 simultaneously>
D	H01L 2224/8569	<administrative transfer to H10W 72/075 and H10W 72/953 simultaneously>
D	H01L 2224/85691	<administrative transfer to H10W 72/075 and H10W 72/953 simultaneously>
D	H01L 2224/85693	<administrative transfer to H10W 72/075 and H10W 72/953 simultaneously>
D	H01L 2224/85694	<administrative transfer to H10W 72/075 and H10W 72/953 simultaneously>
D	H01L 2224/85695	<administrative transfer to H10W 72/075 and H10W 72/953 simultaneously>
D	H01L 2224/85698	<administrative transfer to H10W 72/075 and H10W 72/951 simultaneously>
D	H01L 2224/85699	<administrative transfer to H10W 72/075 and H10W 72/951 simultaneously>
D	H01L 2224/857	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85701	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85705	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85709	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85711	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85713	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85714	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85716	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/85717	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85718	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/8572	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85723	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85724	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85738	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85739	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85744	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85747	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85749	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85755	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85757	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/8576	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85763	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85764	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85766	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85769	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/8577	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85771	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85772	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85773	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85776	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85778	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85779	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/8578	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/85781	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85783	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85784	<administrative transfer to H10W 72/075 and H10W 72/952 simultaneously>
D	H01L 2224/85786	<administrative transfer to H10W 72/075 and H10W 72/953 simultaneously>
D	H01L 2224/85787	<administrative transfer to H10W 72/075 and H10W 72/953 simultaneously>
D	H01L 2224/85788	<administrative transfer to H10W 72/075 and H10W 72/953 simultaneously>
D	H01L 2224/8579	<administrative transfer to H10W 72/075 and H10W 72/953 simultaneously>
D	H01L 2224/85791	<administrative transfer to H10W 72/075 and H10W 72/953 simultaneously>
D	H01L 2224/85793	<administrative transfer to H10W 72/075 and H10W 72/953 simultaneously>
D	H01L 2224/85794	<administrative transfer to H10W 72/075 and H10W 72/953 simultaneously>
D	H01L 2224/85795	<administrative transfer to H10W 72/075 and H10W 72/953 simultaneously>
D	H01L 2224/85798	<administrative transfer to H10W 72/075 and H10W 72/951 simultaneously>
D	H01L 2224/85799	<administrative transfer to H10W 72/075 and H10W 72/951 simultaneously>
D	H01L 2224/858	<administrative transfer to H10W 72/07531>
D	H01L 2224/85801	<administrative transfer to H10W 72/07536>
D	H01L 2224/85805	<administrative transfer to H10W 72/07536>
D	H01L 2224/8581	<administrative transfer to H10W 72/07536>
D	H01L 2224/85815	<administrative transfer to H10W 72/07536>
D	H01L 2224/8582	<administrative transfer to H10W 72/07536>
D	H01L 2224/85825	<administrative transfer to H10W 72/07536>
D	H01L 2224/8583	<administrative transfer to H10W 72/07536>
D	H01L 2224/8584	<administrative transfer to H10W 72/07531>
D	H01L 2224/8585	<administrative transfer to H10W 72/07537>
D	H01L 2224/85855	<administrative transfer to H10W 72/07537>
D	H01L 2224/85856	<administrative transfer to H10W 72/07537>
D	H01L 2224/85859	<administrative transfer to H10W 72/07537>
D	H01L 2224/85862	<administrative transfer to H10W 72/07537>
D	H01L 2224/85865	<administrative transfer to H10W 72/07537>
D	H01L 2224/85868	<administrative transfer to H10W 72/07537>
D	H01L 2224/85871	<administrative transfer to H10W 72/07537>
D	H01L 2224/85874	<administrative transfer to H10W 72/07537>
D	H01L 2224/85877	<administrative transfer to H10W 72/07537>
D	H01L 2224/8588	<administrative transfer to H10W 72/07537>
D	H01L 2224/85885	<administrative transfer to H10W 72/07537>
D	H01L 2224/8589	<administrative transfer to H10W 72/07531>
D	H01L 2224/85893	<administrative transfer to H10W 72/07531>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/85895	<administrative transfer to H10W 80/301>
D	H01L 2224/85897	<administrative transfer to H10W 80/314>
D	H01L 2224/85898	<administrative transfer to H10W 80/327>
D	H01L 2224/85899	<administrative transfer to H10W 72/07531>
D	H01L 2224/859	<administrative transfer to H10W 72/07531>
D	H01L 2224/85909	<administrative transfer to H10W 72/075 and H10W 72/015 simultaneously>
D	H01L 2224/8591	<administrative transfer to H10W 72/075 and H10W 72/01571 simultaneously>
D	H01L 2224/85911	<administrative transfer to H10W 72/075 and H10W 72/01571 simultaneously>
D	H01L 2224/85912	<administrative transfer to H10W 72/075 and H10W 72/01571 simultaneously>
D	H01L 2224/85913	<administrative transfer to H10W 72/075 and H10W 72/01571 simultaneously>
D	H01L 2224/85914	<administrative transfer to H10W 72/075 and H10W 72/01571 simultaneously>
D	H01L 2224/85916	<administrative transfer to H10W 72/075 and H10W 72/01571 simultaneously>
D	H01L 2224/85917	<administrative transfer to H10W 72/075 and H10W 72/01571 simultaneously>
D	H01L 2224/85919	<administrative transfer to H10W 72/075 and H10W 72/01571 simultaneously>
D	H01L 2224/8592	<administrative transfer to H10W 72/075 and H10W 72/01515 simultaneously>
D	H01L 2224/8593	<administrative transfer to H10W 72/075 and H10W 72/01551 simultaneously>
D	H01L 2224/85931	<administrative transfer to H10W 72/075 and H10W 72/01553 simultaneously>
D	H01L 2224/85935	<administrative transfer to H10W 72/075 and H10W 72/01551 simultaneously>
D	H01L 2224/85937	<administrative transfer to H10W 72/075 and H10W 72/01551 simultaneously>
D	H01L 2224/85939	<administrative transfer to H10W 72/075 and H10W 72/01551 simultaneously>
D	H01L 2224/85941	<administrative transfer to H10W 72/075 and H10W 72/01551 simultaneously>
D	H01L 2224/85943	<administrative transfer to H10W 72/075 and H10W 72/01551 simultaneously>
D	H01L 2224/85945	<administrative transfer to H10W 72/075 and H10W 72/01551 simultaneously>
D	H01L 2224/85947	<administrative transfer to H10W 72/075 and H10W 72/01551 simultaneously>
D	H01L 2224/85948	<administrative transfer to H10W 72/075 and H10W 72/01551 simultaneously>
D	H01L 2224/85951	<administrative transfer to H10W 72/075 and H10W 72/01551 simultaneously>
D	H01L 2224/85986	<administrative transfer to H10W 72/075>
D	H01L 2224/86	<administrative transfer to H10W 72/077>
D	H01L 2224/86001	<administrative transfer to H10W 72/077>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/86002	<administrative transfer to H10W 72/077>
D	H01L 2224/86005	<administrative transfer to H10W 72/077>
D	H01L 2224/86007	<administrative transfer to H10W 72/077>
D	H01L 2224/86009	<administrative transfer to H10W 72/077>
D	H01L 2224/8601	<administrative transfer to H10W 72/077>
D	H01L 2224/8603	<administrative transfer to H10W 72/077>
D	H01L 2224/86031	<administrative transfer to H10W 72/077>
D	H01L 2224/86035	<administrative transfer to H10W 72/077>
D	H01L 2224/86039	<administrative transfer to H10W 72/077>
D	H01L 2224/86045	<administrative transfer to H10W 72/077>
D	H01L 2224/86047	<administrative transfer to H10W 72/077>
D	H01L 2224/86048	<administrative transfer to H10W 72/077>
D	H01L 2224/86051	<administrative transfer to H10W 72/077>
D	H01L 2224/86053	<administrative transfer to H10W 72/077>
D	H01L 2224/86054	<administrative transfer to H10W 72/077>
D	H01L 2224/86085	<administrative transfer to H10W 72/077>
D	H01L 2224/8609	<administrative transfer to H10W 72/077>
D	H01L 2224/86091	<administrative transfer to H10W 72/077>
D	H01L 2224/86095	<administrative transfer to H10W 72/077>
D	H01L 2224/86096	<administrative transfer to H10W 72/077>
D	H01L 2224/86097	<administrative transfer to H10W 72/077>
D	H01L 2224/86098	<administrative transfer to H10W 72/077>
D	H01L 2224/86099	<administrative transfer to H10W 72/077>
D	H01L 2224/861	<administrative transfer to H10W 72/077>
D	H01L 2224/8611	<administrative transfer to H10W 72/077>
D	H01L 2224/8612	<administrative transfer to H10W 72/077>
D	H01L 2224/86121	<administrative transfer to H10W 72/077>
D	H01L 2224/86122	<administrative transfer to H10W 72/077>
D	H01L 2224/8613	<administrative transfer to H10W 72/077>
D	H01L 2224/86132	<administrative transfer to H10W 72/077>
D	H01L 2224/86136	<administrative transfer to H10W 72/077>
D	H01L 2224/86138	<administrative transfer to H10W 72/077>
D	H01L 2224/86143	<administrative transfer to H10W 72/077>
D	H01L 2224/86148	<administrative transfer to H10W 72/077>
D	H01L 2224/86149	<administrative transfer to H10W 72/077>
D	H01L 2224/8615	<administrative transfer to H10W 72/077>
D	H01L 2224/8616	<administrative transfer to H10W 72/077>
D	H01L 2224/86169	<administrative transfer to H10W 72/077>
D	H01L 2224/8617	<administrative transfer to H10W 72/077>
D	H01L 2224/8618	<administrative transfer to H10W 72/077>
D	H01L 2224/86181	<administrative transfer to H10W 72/077>
D	H01L 2224/86186	<administrative transfer to H10W 72/077>
D	H01L 2224/86191	<administrative transfer to H10W 72/077>
D	H01L 2224/862	<administrative transfer to H10W 72/077>
D	H01L 2224/86201	<administrative transfer to H10W 72/077>
D	H01L 2224/86203	<administrative transfer to H10W 72/077>
D	H01L 2224/86205	<administrative transfer to H10W 72/077>
D	H01L 2224/86207	<administrative transfer to H10W 72/077>
D	H01L 2224/8621	<administrative transfer to H10W 72/077>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/86212	<administrative transfer to H10W 72/077>
D	H01L 2224/86214	<administrative transfer to H10W 72/077>
D	H01L 2224/8623	<administrative transfer to H10W 72/077>
D	H01L 2224/86232	<administrative transfer to H10W 72/077>
D	H01L 2224/86234	<administrative transfer to H10W 72/077>
D	H01L 2224/86236	<administrative transfer to H10W 72/077>
D	H01L 2224/86237	<administrative transfer to H10W 72/077>
D	H01L 2224/86238	<administrative transfer to H10W 72/077>
D	H01L 2224/8634	<administrative transfer to H10W 72/077>
D	H01L 2224/86345	<administrative transfer to H10W 72/077>
D	H01L 2224/86355	<administrative transfer to H10W 72/077>
D	H01L 2224/86359	<administrative transfer to H10W 72/077>
D	H01L 2224/8636	<administrative transfer to H10W 72/077>
D	H01L 2224/86365	<administrative transfer to H10W 72/077>
D	H01L 2224/86375	<administrative transfer to H10W 72/077>
D	H01L 2224/86379	<administrative transfer to H10W 72/077>
D	H01L 2224/8638	<administrative transfer to H10W 72/077>
D	H01L 2224/86385	<administrative transfer to H10W 72/077>
D	H01L 2224/86395	<administrative transfer to H10W 72/077>
D	H01L 2224/86399	<administrative transfer to H10W 72/077>
D	H01L 2224/868	<administrative transfer to H10W 72/077>
D	H01L 2224/86801	<administrative transfer to H10W 72/077>
D	H01L 2224/86805	<administrative transfer to H10W 72/077>
D	H01L 2224/8681	<administrative transfer to H10W 72/077>
D	H01L 2224/86815	<administrative transfer to H10W 72/077>
D	H01L 2224/8682	<administrative transfer to H10W 72/077>
D	H01L 2224/86825	<administrative transfer to H10W 72/077>
D	H01L 2224/8683	<administrative transfer to H10W 72/077>
D	H01L 2224/8684	<administrative transfer to H10W 72/077>
D	H01L 2224/8685	<administrative transfer to H10W 72/077>
D	H01L 2224/86855	<administrative transfer to H10W 72/077>
D	H01L 2224/86856	<administrative transfer to H10W 72/077>
D	H01L 2224/86859	<administrative transfer to H10W 72/077>
D	H01L 2224/86862	<administrative transfer to H10W 72/077>
D	H01L 2224/86865	<administrative transfer to H10W 72/077>
D	H01L 2224/86868	<administrative transfer to H10W 72/077>
D	H01L 2224/86871	<administrative transfer to H10W 72/077>
D	H01L 2224/86874	<administrative transfer to H10W 72/077>
D	H01L 2224/86877	<administrative transfer to H10W 72/077>
D	H01L 2224/8688	<administrative transfer to H10W 72/077>
D	H01L 2224/86885	<administrative transfer to H10W 72/077>
D	H01L 2224/8689	<administrative transfer to H10W 72/077>
D	H01L 2224/86893	<administrative transfer to H10W 72/077>
D	H01L 2224/86895	<administrative transfer to H10W 72/077>
D	H01L 2224/86896	<administrative transfer to H10W 72/077>
D	H01L 2224/86897	<administrative transfer to H10W 72/077>
D	H01L 2224/86899	<administrative transfer to H10W 72/077>
D	H01L 2224/869	<administrative transfer to H10W 72/077>
D	H01L 2224/86909	<administrative transfer to H10W 72/077>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/8691	<administrative transfer to H10W 72/077>
D	H01L 2224/8693	<administrative transfer to H10W 72/077>
D	H01L 2224/86931	<administrative transfer to H10W 72/077>
D	H01L 2224/86935	<administrative transfer to H10W 72/077>
D	H01L 2224/86939	<administrative transfer to H10W 72/077>
D	H01L 2224/86945	<administrative transfer to H10W 72/077>
D	H01L 2224/86947	<administrative transfer to H10W 72/077>
D	H01L 2224/86948	<administrative transfer to H10W 72/077>
D	H01L 2224/86951	<administrative transfer to H10W 72/077>
D	H01L 2224/86986	<administrative transfer to H10W 72/077>
D	H01L 2224/89	<administrative transfer to H10W 72/00>
D	H01L 2224/90	<administrative transfer to H10W 72/00>
D	H01L 2224/91	<administrative transfer to H10W 99/00>
D	H01L 2224/92	<administrative transfer to H10W 99/00>
D	H01L 2224/9201	<administrative transfer to H10W 99/00>
D	H01L 2224/9202	<administrative transfer to H10W 99/00>
D	H01L 2224/9205	<administrative transfer to H10W 99/00>
D	H01L 2224/921	<administrative transfer to H10W 99/00>
D	H01L 2224/9211	<administrative transfer to H10W 99/00>
D	H01L 2224/9212	<administrative transfer to H10W 99/00>
D	H01L 2224/92122	<administrative transfer to H10W 72/072>
D	H01L 2224/92124	<administrative transfer to H10W 72/072 and H10W 70/099 simultaneously>
D	H01L 2224/92125	<administrative transfer to H10W 72/072 and H10W 72/073 simultaneously>
D	H01L 2224/92127	<administrative transfer to H10W 72/072 and H10W 72/075 simultaneously>
D	H01L 2224/92132	<administrative transfer to H10W 70/099>
D	H01L 2224/92133	<administrative transfer to H10W 70/099 and H10W 72/072 simultaneously>
D	H01L 2224/92135	<administrative transfer to H10W 70/099 and H10W 72/073 simultaneously>
D	H01L 2224/92136	<administrative transfer to H10W 70/099 and H10W 72/076 simultaneously>
D	H01L 2224/92137	<administrative transfer to H10W 70/099 and H10W 72/075 simultaneously>
D	H01L 2224/92138	<administrative transfer to H10W 70/099 and H10W 72/077 simultaneously>
D	H01L 2224/92142	<administrative transfer to H10W 72/073>
D	H01L 2224/92143	<administrative transfer to H10W 72/073 and H10W 72/072 simultaneously>
D	H01L 2224/92144	<administrative transfer to H10W 72/073 and H10W 70/093 simultaneously>
D	H01L 2224/92147	<administrative transfer to H10W 72/073 and H10W 72/075 simultaneously>
D	H01L 2224/92148	<administrative transfer to H10W 72/073 and H10W 72/077 simultaneously>
D	H01L 2224/92152	<administrative transfer to H10W 72/076>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/92153	<administrative transfer to H10W 72/076 and H10W 72/072 simultaneously>
D	H01L 2224/92155	<administrative transfer to H10W 72/073 and H10W 72/076 simultaneously>
D	H01L 2224/92157	<administrative transfer to H10W 72/076 and H10W 72/075 simultaneously>
D	H01L 2224/92158	<administrative transfer to H10W 72/076 and H10W 72/077 simultaneously>
D	H01L 2224/92162	<administrative transfer to H10W 72/075>
D	H01L 2224/92163	<administrative transfer to H10W 72/075 and H10W 72/072 simultaneously>
D	H01L 2224/92164	<administrative transfer to H10W 72/075 and H10W 70/093 simultaneously>
D	H01L 2224/92165	<administrative transfer to H10W 72/075 and H10W 72/073 simultaneously>
D	H01L 2224/92166	<administrative transfer to H10W 72/075 and H10W 72/076 simultaneously>
D	H01L 2224/92168	<administrative transfer to H10W 72/075 and H10W 72/077 simultaneously>
D	H01L 2224/92172	<administrative transfer to H10W 72/077>
D	H01L 2224/92173	<administrative transfer to H10W 72/077 and H10W 72/072 simultaneously>
D	H01L 2224/92174	<administrative transfer to H10W 72/077 and H10W 70/093 simultaneously>
D	H01L 2224/92175	<administrative transfer to H10W 72/077 and H10W 72/073 simultaneously>
D	H01L 2224/92176	<administrative transfer to H10W 72/077 and H10W 72/076 simultaneously>
D	H01L 2224/92177	<administrative transfer to H10W 72/077 and H10W 72/075 simultaneously>
D	H01L 2224/922	<no transfer>
D	H01L 2224/9221	<no transfer>
D	H01L 2224/9222	<no transfer>
D	H01L 2224/92222	<administrative transfer to H10W 72/072>
D	H01L 2224/92224	<administrative transfer to H10W 72/072 and H10W 70/099 simultaneously>
D	H01L 2224/92225	<administrative transfer to H10W 72/072 and H10W 72/073 simultaneously>
D	H01L 2224/92226	<administrative transfer to H10W 72/072 and H10W 72/076 simultaneously>
D	H01L 2224/92227	<administrative transfer to H10W 72/072 and H10W 72/075 simultaneously>
D	H01L 2224/92228	<administrative transfer to H10W 72/072 and H10W 72/077 simultaneously>
D	H01L 2224/92242	<administrative transfer to H10W 72/073>
D	H01L 2224/92244	<administrative transfer to H10W 72/073 and H10W 70/099 simultaneously>
D	H01L 2224/92246	<administrative transfer to H10W 72/073 and H10W 72/076 simultaneously>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2224/92247	<administrative transfer to H10W 72/073 and H10W 72/075 simultaneously>
D	H01L 2224/92248	<administrative transfer to H10W 72/073 and H10W 72/077 simultaneously>
D	H01L 2224/92252	<administrative transfer to H10W 72/076>
D	H01L 2224/92253	<administrative transfer to H10W 72/076 and H10W 72/072 simultaneously>
D	H01L 2224/92255	<administrative transfer to H10W 72/076 and H10W 72/073 simultaneously>
D	H01L 2224/93	<administrative transfer to H10W 72/0198>
D	H01L 2224/94	<administrative transfer to H10W 72/0198>
D	H01L 2224/95	<administrative transfer to H10W 72/0198>
D	H01L 2224/95001	<administrative transfer to H10W 72/0198>
D	H01L 2224/95053	<administrative transfer to H10W 72/0198>
D	H01L 2224/95085	<administrative transfer to H10W 72/0198>
D	H01L 2224/95091	<administrative transfer to H10W 72/0198>
D	H01L 2224/95092	<administrative transfer to H10W 72/0198>
D	H01L 2224/95093	<administrative transfer to H10W 72/0198>
D	H01L 2224/951	<administrative transfer to H10W 72/0198>
D	H01L 2224/95101	<administrative transfer to H10W 72/0198>
D	H01L 2224/95102	<administrative transfer to H10W 72/0198>
D	H01L 2224/9511	<administrative transfer to H10W 72/0198>
D	H01L 2224/95115	<administrative transfer to H10W 72/0198>
D	H01L 2224/9512	<administrative transfer to H10W 72/0198>
D	H01L 2224/95121	<administrative transfer to H10W 72/0198>
D	H01L 2224/95122	<administrative transfer to H10W 72/0198>
D	H01L 2224/95123	<administrative transfer to H10W 72/0198>
D	H01L 2224/95133	<administrative transfer to H10W 72/0198>
D	H01L 2224/95134	<administrative transfer to H10W 72/0198>
D	H01L 2224/95136	<administrative transfer to H10W 72/0198>
D	H01L 2224/95143	<administrative transfer to H10W 72/0198>
D	H01L 2224/95144	<administrative transfer to H10W 72/0198>
D	H01L 2224/95145	<administrative transfer to H10W 72/0198>
D	H01L 2224/95146	<administrative transfer to H10W 72/0198>
D	H01L 2224/95147	<administrative transfer to H10W 72/0198>
D	H01L 2224/95148	<administrative transfer to H10W 72/0198>
D	H01L 2224/96	<administrative transfer to H10W 72/0198>
D	H01L 2224/97	<administrative transfer to H10W 72/0198>
D	H01L 2224/98	<administrative transfer to H10W 72/071>
D	H01L 2225/00	<administrative transfer to H10W 90/00>
D	H01L 2225/03	<administrative transfer to H10W 90/00>
D	H01L 2225/04	<administrative transfer to H10W 90/00>
D	H01L 2225/065	<administrative transfer to H10W 90/00>
D	H01L 2225/06503	<administrative transfer to H10W 90/20>
D	H01L 2225/06506	<administrative transfer to H10W 90/752>
D	H01L 2225/0651	<administrative transfer to H10W 90/754>
D	H01L 2225/06513	<administrative transfer to H10W 90/722>
D	H01L 2225/06517	<administrative transfer to H10W 90/724>
D	H01L 2225/0652	<administrative transfer to H10W 90/721>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2225/06524	<administrative transfer to H10W 90/20>
D	H01L 2225/06527	<administrative transfer to H10W 72/01>
D	H01L 2225/06531	<administrative transfer to H10W 90/293>
D	H01L 2225/06534	<administrative transfer to H10W 90/295>
D	H01L 2225/06537	<administrative transfer to H10W 42/271>
D	H01L 2225/06541	<administrative transfer to H10W 90/297>
D	H01L 2225/06544	<administrative transfer to H10W 90/297>
D	H01L 2225/06548	<administrative transfer to H10W 72/823>
D	H01L 2225/06551	<administrative transfer to H10W 72/834>
D	H01L 2225/06555	<administrative transfer to H10W 90/20>
D	H01L 2225/06558	<administrative transfer to H10W 90/271>
D	H01L 2225/06562	<administrative transfer to H10W 90/24>
D	H01L 2225/06565	<administrative transfer to H10W 90/26>
D	H01L 2225/06568	<administrative transfer to H10W 90/28>
D	H01L 2225/06572	<administrative transfer to H10W 90/22>
D	H01L 2225/06575	<administrative transfer to H10W 90/231>
D	H01L 2225/06579	<administrative transfer to H10W 72/60>
D	H01L 2225/06582	<administrative transfer to H10W 90/291>
D	H01L 2225/06586	<administrative transfer to H10W 90/291>
D	H01L 2225/06589	<administrative transfer to H10W 90/288>
D	H01L 2225/06593	<administrative transfer to H10W 46/00>
D	H01L 2225/06596	<administrative transfer to H10W 90/284>
D	H01L 2225/10	<administrative transfer to H10W 90/20>
D	H01L 2225/1005	<administrative transfer to H10W 90/20>
D	H01L 2225/1011	<administrative transfer to H10W 90/20>
D	H01L 2225/1017	<administrative transfer to H10W 90/20>
D	H01L 2225/1023	<administrative transfer to H10W 70/60>
D	H01L 2225/1029	<administrative transfer to H10W 70/40>
D	H01L 2225/1035	<administrative transfer to H10W 70/60>
D	H01L 2225/1041	<administrative transfer to H10W 70/60>
D	H01L 2225/1047	<administrative transfer to H10W 90/701>
D	H01L 2225/1052	<administrative transfer to H10W 90/752>
D	H01L 2225/1058	<administrative transfer to H10W 90/722>
D	H01L 2225/1064	<administrative transfer to H10W 72/801>
D	H01L 2225/107	<administrative transfer to H10W 70/60>
D	H01L 2225/1076	<administrative transfer to H10W 90/291>
D	H01L 2225/1082	<administrative transfer to H10W 90/291>
D	H01L 2225/1088	<administrative transfer to H10W 90/291>
D	H01L 2225/1094	<administrative transfer to H10W 90/288>
D	H01L 2924/00	<no transfer>
D	H01L 2924/0001	<no transfer>
D	H01L 2924/00011	<no transfer>
D	H01L 2924/00012	<no transfer>
D	H01L 2924/00013	<no transfer>
D	H01L 2924/00014	<no transfer>
D	H01L 2924/00015	<no transfer>
D	H01L 2924/0002	<no transfer>
D	H01L 2924/01	<no transfer>
D	H01L 2924/01001	<no transfer>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2924/01002	<no transfer>
D	H01L 2924/01003	<no transfer>
D	H01L 2924/01004	<no transfer>
D	H01L 2924/01005	<no transfer>
D	H01L 2924/01006	<no transfer>
D	H01L 2924/01007	<no transfer>
D	H01L 2924/01008	<no transfer>
D	H01L 2924/01009	<no transfer>
D	H01L 2924/0101	<no transfer>
D	H01L 2924/01011	<no transfer>
D	H01L 2924/01012	<no transfer>
D	H01L 2924/01013	<no transfer>
D	H01L 2924/01014	<no transfer>
D	H01L 2924/01015	<no transfer>
D	H01L 2924/01016	<no transfer>
D	H01L 2924/01017	<no transfer>
D	H01L 2924/01018	<no transfer>
D	H01L 2924/01019	<no transfer>
D	H01L 2924/0102	<no transfer>
D	H01L 2924/01021	<no transfer>
D	H01L 2924/01022	<no transfer>
D	H01L 2924/01023	<no transfer>
D	H01L 2924/01024	<no transfer>
D	H01L 2924/01025	<no transfer>
D	H01L 2924/01026	<no transfer>
D	H01L 2924/01027	<no transfer>
D	H01L 2924/01028	<no transfer>
D	H01L 2924/01029	<no transfer>
D	H01L 2924/0103	<no transfer>
D	H01L 2924/01031	<no transfer>
D	H01L 2924/01032	<no transfer>
D	H01L 2924/01033	<no transfer>
D	H01L 2924/01034	<no transfer>
D	H01L 2924/01035	<no transfer>
D	H01L 2924/01036	<no transfer>
D	H01L 2924/01037	<no transfer>
D	H01L 2924/01038	<no transfer>
D	H01L 2924/01039	<no transfer>
D	H01L 2924/0104	<no transfer>
D	H01L 2924/01041	<no transfer>
D	H01L 2924/01042	<no transfer>
D	H01L 2924/01043	<no transfer>
D	H01L 2924/01044	<no transfer>
D	H01L 2924/01045	<no transfer>
D	H01L 2924/01046	<no transfer>
D	H01L 2924/01047	<no transfer>
D	H01L 2924/01048	<no transfer>
D	H01L 2924/01049	<no transfer>
D	H01L 2924/0105	<no transfer>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2924/01051	<no transfer>
D	H01L 2924/01052	<no transfer>
D	H01L 2924/01053	<no transfer>
D	H01L 2924/01054	<no transfer>
D	H01L 2924/01055	<no transfer>
D	H01L 2924/01056	<no transfer>
D	H01L 2924/01057	<no transfer>
D	H01L 2924/01058	<no transfer>
D	H01L 2924/01059	<no transfer>
D	H01L 2924/0106	<no transfer>
D	H01L 2924/01061	<no transfer>
D	H01L 2924/01062	<no transfer>
D	H01L 2924/01063	<no transfer>
D	H01L 2924/01064	<no transfer>
D	H01L 2924/01065	<no transfer>
D	H01L 2924/01066	<no transfer>
D	H01L 2924/01067	<no transfer>
D	H01L 2924/01068	<no transfer>
D	H01L 2924/01069	<no transfer>
D	H01L 2924/0107	<no transfer>
D	H01L 2924/01071	<no transfer>
D	H01L 2924/01072	<no transfer>
D	H01L 2924/01073	<no transfer>
D	H01L 2924/01074	<no transfer>
D	H01L 2924/01075	<no transfer>
D	H01L 2924/01076	<no transfer>
D	H01L 2924/01077	<no transfer>
D	H01L 2924/01078	<no transfer>
D	H01L 2924/01079	<no transfer>
D	H01L 2924/0108	<no transfer>
D	H01L 2924/01081	<no transfer>
D	H01L 2924/01082	<no transfer>
D	H01L 2924/01083	<no transfer>
D	H01L 2924/01084	<no transfer>
D	H01L 2924/01085	<no transfer>
D	H01L 2924/01086	<no transfer>
D	H01L 2924/01087	<no transfer>
D	H01L 2924/01088	<no transfer>
D	H01L 2924/01089	<no transfer>
D	H01L 2924/0109	<no transfer>
D	H01L 2924/01091	<no transfer>
D	H01L 2924/01092	<no transfer>
D	H01L 2924/01093	<no transfer>
D	H01L 2924/01094	<no transfer>
D	H01L 2924/011	<no transfer>
D	H01L 2924/01101	<no transfer>
D	H01L 2924/01102	<no transfer>
D	H01L 2924/01103	<no transfer>
D	H01L 2924/01104	<no transfer>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2924/01105	<no transfer>
D	H01L 2924/01106	<no transfer>
D	H01L 2924/01107	<no transfer>
D	H01L 2924/01108	<no transfer>
D	H01L 2924/01109	<no transfer>
D	H01L 2924/0111	<no transfer>
D	H01L 2924/01111	<no transfer>
D	H01L 2924/01112	<no transfer>
D	H01L 2924/012	<no transfer>
D	H01L 2924/01201	<no transfer>
D	H01L 2924/01202	<no transfer>
D	H01L 2924/01203	<no transfer>
D	H01L 2924/01204	<no transfer>
D	H01L 2924/01205	<no transfer>
D	H01L 2924/01206	<no transfer>
D	H01L 2924/01207	<no transfer>
D	H01L 2924/01208	<no transfer>
D	H01L 2924/013	<no transfer>
D	H01L 2924/0132	<no transfer>
D	H01L 2924/01321	<no transfer>
D	H01L 2924/01322	<no transfer>
D	H01L 2924/01323	<no transfer>
D	H01L 2924/01324	<no transfer>
D	H01L 2924/01325	<no transfer>
D	H01L 2924/01326	<no transfer>
D	H01L 2924/01327	<no transfer>
D	H01L 2924/0133	<no transfer>
D	H01L 2924/0134	<no transfer>
D	H01L 2924/0135	<no transfer>
D	H01L 2924/014	<no transfer>
D	H01L 2924/01402	<no transfer>
D	H01L 2924/01403	<no transfer>
D	H01L 2924/01404	<no transfer>
D	H01L 2924/01405	<no transfer>
D	H01L 2924/042	<no transfer>
D	H01L 2924/0421	<no transfer>
D	H01L 2924/0422	<no transfer>
D	H01L 2924/0423	<no transfer>
D	H01L 2924/0424	<no transfer>
D	H01L 2924/0425	<no transfer>
D	H01L 2924/0426	<no transfer>
D	H01L 2924/0427	<no transfer>
D	H01L 2924/0428	<no transfer>
D	H01L 2924/0429	<no transfer>
D	H01L 2924/044	<no transfer>
D	H01L 2924/0441	<no transfer>
D	H01L 2924/0442	<no transfer>
D	H01L 2924/0443	<no transfer>
D	H01L 2924/0444	<no transfer>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2924/0445	<no transfer>
D	H01L 2924/0446	<no transfer>
D	H01L 2924/0449	<no transfer>
D	H01L 2924/04491	<no transfer>
D	H01L 2924/04492	<no transfer>
D	H01L 2924/04494	<no transfer>
D	H01L 2924/045	<no transfer>
D	H01L 2924/0451	<no transfer>
D	H01L 2924/0452	<no transfer>
D	H01L 2924/0453	<no transfer>
D	H01L 2924/0454	<no transfer>
D	H01L 2924/04541	<no transfer>
D	H01L 2924/0455	<no transfer>
D	H01L 2924/0456	<no transfer>
D	H01L 2924/04563	<no transfer>
D	H01L 2924/0457	<no transfer>
D	H01L 2924/0458	<no transfer>
D	H01L 2924/0459	<no transfer>
D	H01L 2924/046	<no transfer>
D	H01L 2924/0461	<no transfer>
D	H01L 2924/0462	<no transfer>
D	H01L 2924/0463	<no transfer>
D	H01L 2924/0464	<no transfer>
D	H01L 2924/04642	<no transfer>
D	H01L 2924/0465	<no transfer>
D	H01L 2924/0466	<no transfer>
D	H01L 2924/0469	<no transfer>
D	H01L 2924/04691	<no transfer>
D	H01L 2924/04692	<no transfer>
D	H01L 2924/04694	<no transfer>
D	H01L 2924/047	<no transfer>
D	H01L 2924/0471	<no transfer>
D	H01L 2924/0472	<no transfer>
D	H01L 2924/0473	<no transfer>
D	H01L 2924/0474	<no transfer>
D	H01L 2924/0475	<no transfer>
D	H01L 2924/0476	<no transfer>
D	H01L 2924/0477	<no transfer>
D	H01L 2924/0478	<no transfer>
D	H01L 2924/0479	<no transfer>
D	H01L 2924/048	<no transfer>
D	H01L 2924/0481	<no transfer>
D	H01L 2924/0482	<no transfer>
D	H01L 2924/0483	<no transfer>
D	H01L 2924/0484	<no transfer>
D	H01L 2924/0485	<no transfer>
D	H01L 2924/0486	<no transfer>
D	H01L 2924/0489	<no transfer>
D	H01L 2924/04891	<no transfer>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2924/04892	<no transfer>
D	H01L 2924/04894	<no transfer>
D	H01L 2924/049	<no transfer>
D	H01L 2924/0491	<no transfer>
D	H01L 2924/0492	<no transfer>
D	H01L 2924/0493	<no transfer>
D	H01L 2924/0494	<no transfer>
D	H01L 2924/04941	<no transfer>
D	H01L 2924/0495	<no transfer>
D	H01L 2924/04953	<no transfer>
D	H01L 2924/0496	<no transfer>
D	H01L 2924/0497	<no transfer>
D	H01L 2924/0498	<no transfer>
D	H01L 2924/0499	<no transfer>
D	H01L 2924/05	<no transfer>
D	H01L 2924/0501	<no transfer>
D	H01L 2924/0502	<no transfer>
D	H01L 2924/0503	<no transfer>
D	H01L 2924/05032	<no transfer>
D	H01L 2924/0504	<no transfer>
D	H01L 2924/05042	<no transfer>
D	H01L 2924/0505	<no transfer>
D	H01L 2924/0506	<no transfer>
D	H01L 2924/0509	<no transfer>
D	H01L 2924/05091	<no transfer>
D	H01L 2924/05092	<no transfer>
D	H01L 2924/05094	<no transfer>
D	H01L 2924/051	<no transfer>
D	H01L 2924/0511	<no transfer>
D	H01L 2924/0512	<no transfer>
D	H01L 2924/0513	<no transfer>
D	H01L 2924/0514	<no transfer>
D	H01L 2924/0515	<no transfer>
D	H01L 2924/0516	<no transfer>
D	H01L 2924/0517	<no transfer>
D	H01L 2924/0518	<no transfer>
D	H01L 2924/0519	<no transfer>
D	H01L 2924/052	<no transfer>
D	H01L 2924/0521	<no transfer>
D	H01L 2924/0522	<no transfer>
D	H01L 2924/0523	<no transfer>
D	H01L 2924/0524	<no transfer>
D	H01L 2924/0525	<no transfer>
D	H01L 2924/0526	<no transfer>
D	H01L 2924/0529	<no transfer>
D	H01L 2924/05291	<no transfer>
D	H01L 2924/05292	<no transfer>
D	H01L 2924/05294	<no transfer>
D	H01L 2924/053	<no transfer>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2924/0531	<no transfer>
D	H01L 2924/0532	<no transfer>
D	H01L 2924/0533	<no transfer>
D	H01L 2924/0534	<no transfer>
D	H01L 2924/05341	<no transfer>
D	H01L 2924/05342	<no transfer>
D	H01L 2924/0535	<no transfer>
D	H01L 2924/0536	<no transfer>
D	H01L 2924/0537	<no transfer>
D	H01L 2924/0538	<no transfer>
D	H01L 2924/05381	<no transfer>
D	H01L 2924/0539	<no transfer>
D	H01L 2924/054	<no transfer>
D	H01L 2924/0541	<no transfer>
D	H01L 2924/0542	<no transfer>
D	H01L 2924/0543	<no transfer>
D	H01L 2924/05432	<no transfer>
D	H01L 2924/0544	<no transfer>
D	H01L 2924/05442	<no transfer>
D	H01L 2924/0545	<no transfer>
D	H01L 2924/0546	<no transfer>
D	H01L 2924/0549	<no transfer>
D	H01L 2924/05491	<no transfer>
D	H01L 2924/05492	<no transfer>
D	H01L 2924/05494	<no transfer>
D	H01L 2924/055	<no transfer>
D	H01L 2924/0551	<no transfer>
D	H01L 2924/0552	<no transfer>
D	H01L 2924/0553	<no transfer>
D	H01L 2924/0554	<no transfer>
D	H01L 2924/0555	<no transfer>
D	H01L 2924/0556	<no transfer>
D	H01L 2924/0557	<no transfer>
D	H01L 2924/0558	<no transfer>
D	H01L 2924/0559	<no transfer>
D	H01L 2924/056	<no transfer>
D	H01L 2924/0561	<no transfer>
D	H01L 2924/0562	<no transfer>
D	H01L 2924/0563	<no transfer>
D	H01L 2924/0564	<no transfer>
D	H01L 2924/0565	<no transfer>
D	H01L 2924/0566	<no transfer>
D	H01L 2924/0569	<no transfer>
D	H01L 2924/05691	<no transfer>
D	H01L 2924/05692	<no transfer>
D	H01L 2924/05694	<no transfer>
D	H01L 2924/057	<no transfer>
D	H01L 2924/0571	<no transfer>
D	H01L 2924/0572	<no transfer>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2924/0573	<no transfer>
D	H01L 2924/0574	<no transfer>
D	H01L 2924/0575	<no transfer>
D	H01L 2924/0576	<no transfer>
D	H01L 2924/0577	<no transfer>
D	H01L 2924/0578	<no transfer>
D	H01L 2924/0579	<no transfer>
D	H01L 2924/058	<no transfer>
D	H01L 2924/0581	<no transfer>
D	H01L 2924/0582	<no transfer>
D	H01L 2924/0583	<no transfer>
D	H01L 2924/0584	<no transfer>
D	H01L 2924/0585	<no transfer>
D	H01L 2924/0586	<no transfer>
D	H01L 2924/0589	<no transfer>
D	H01L 2924/05891	<no transfer>
D	H01L 2924/05892	<no transfer>
D	H01L 2924/05894	<no transfer>
D	H01L 2924/059	<no transfer>
D	H01L 2924/05991	<no transfer>
D	H01L 2924/05992	<no transfer>
D	H01L 2924/05994	<no transfer>
D	H01L 2924/06	<no transfer>
D	H01L 2924/061	<no transfer>
D	H01L 2924/0615	<no transfer>
D	H01L 2924/062	<no transfer>
D	H01L 2924/0625	<no transfer>
D	H01L 2924/063	<no transfer>
D	H01L 2924/0635	<no transfer>
D	H01L 2924/064	<no transfer>
D	H01L 2924/0645	<no transfer>
D	H01L 2924/065	<no transfer>
D	H01L 2924/0655	<no transfer>
D	H01L 2924/066	<no transfer>
D	H01L 2924/0665	<no transfer>
D	H01L 2924/067	<no transfer>
D	H01L 2924/0675	<no transfer>
D	H01L 2924/068	<no transfer>
D	H01L 2924/0685	<no transfer>
D	H01L 2924/069	<no transfer>
D	H01L 2924/0695	<no transfer>
D	H01L 2924/07	<no transfer>
D	H01L 2924/07001	<no transfer>
D	H01L 2924/07025	<no transfer>
D	H01L 2924/0705	<no transfer>
D	H01L 2924/0715	<no transfer>
D	H01L 2924/078	<no transfer>
D	H01L 2924/07802	<no transfer>
D	H01L 2924/0781	<no transfer>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2924/07811	<no transfer>
D	H01L 2924/07812	<no transfer>
D	H01L 2924/0782	<no transfer>
D	H01L 2924/095	<no transfer>
D	H01L 2924/0951	<no transfer>
D	H01L 2924/09511	<no transfer>
D	H01L 2924/09512	<no transfer>
D	H01L 2924/09522	<no transfer>
D	H01L 2924/09523	<no transfer>
D	H01L 2924/096	<no transfer>
D	H01L 2924/097	<no transfer>
D	H01L 2924/09701	<no transfer>
D	H01L 2924/10	<no transfer>
D	H01L 2924/1011	<no transfer>
D	H01L 2924/1015	<no transfer>
D	H01L 2924/10155	<no transfer>
D	H01L 2924/10156	<no transfer>
D	H01L 2924/10157	<no transfer>
D	H01L 2924/10158	<no transfer>
D	H01L 2924/1016	<no transfer>
D	H01L 2924/10161	<no transfer>
D	H01L 2924/10162	<no transfer>
D	H01L 2924/1017	<no transfer>
D	H01L 2924/102	<no transfer>
D	H01L 2924/1025	<no transfer>
D	H01L 2924/10251	<no transfer>
D	H01L 2924/10252	<no transfer>
D	H01L 2924/10253	<no transfer>
D	H01L 2924/10254	<no transfer>
D	H01L 2924/1026	<no transfer>
D	H01L 2924/1027	<no transfer>
D	H01L 2924/10271	<no transfer>
D	H01L 2924/10272	<no transfer>
D	H01L 2924/1032	<no transfer>
D	H01L 2924/10321	<no transfer>
D	H01L 2924/10322	<no transfer>
D	H01L 2924/10323	<no transfer>
D	H01L 2924/10324	<no transfer>
D	H01L 2924/10325	<no transfer>
D	H01L 2924/10326	<no transfer>
D	H01L 2924/10327	<no transfer>
D	H01L 2924/10328	<no transfer>
D	H01L 2924/10329	<no transfer>
D	H01L 2924/1033	<no transfer>
D	H01L 2924/10331	<no transfer>
D	H01L 2924/10332	<no transfer>
D	H01L 2924/10333	<no transfer>
D	H01L 2924/10334	<no transfer>
D	H01L 2924/10335	<no transfer>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2924/10336	<no transfer>
D	H01L 2924/10337	<no transfer>
D	H01L 2924/10338	<no transfer>
D	H01L 2924/10339	<no transfer>
D	H01L 2924/1034	<no transfer>
D	H01L 2924/10341	<no transfer>
D	H01L 2924/10342	<no transfer>
D	H01L 2924/10343	<no transfer>
D	H01L 2924/10344	<no transfer>
D	H01L 2924/10345	<no transfer>
D	H01L 2924/10346	<no transfer>
D	H01L 2924/10347	<no transfer>
D	H01L 2924/10348	<no transfer>
D	H01L 2924/10349	<no transfer>
D	H01L 2924/1035	<no transfer>
D	H01L 2924/10351	<no transfer>
D	H01L 2924/10352	<no transfer>
D	H01L 2924/10353	<no transfer>
D	H01L 2924/10354	<no transfer>
D	H01L 2924/10355	<no transfer>
D	H01L 2924/10356	<no transfer>
D	H01L 2924/10357	<no transfer>
D	H01L 2924/10358	<no transfer>
D	H01L 2924/10359	<no transfer>
D	H01L 2924/1036	<no transfer>
D	H01L 2924/1037	<no transfer>
D	H01L 2924/10371	<no transfer>
D	H01L 2924/10372	<no transfer>
D	H01L 2924/10373	<no transfer>
D	H01L 2924/10375	<no transfer>
D	H01L 2924/10376	<no transfer>
D	H01L 2924/10377	<no transfer>
D	H01L 2924/10378	<no transfer>
D	H01L 2924/10379	<no transfer>
D	H01L 2924/1038	<no transfer>
D	H01L 2924/10381	<no transfer>
D	H01L 2924/1042	<no transfer>
D	H01L 2924/10421	<no transfer>
D	H01L 2924/1047	<no transfer>
D	H01L 2924/10471	<no transfer>
D	H01L 2924/1052	<no transfer>
D	H01L 2924/10521	<no transfer>
D	H01L 2924/10522	<no transfer>
D	H01L 2924/10523	<no transfer>
D	H01L 2924/10524	<no transfer>
D	H01L 2924/10525	<no transfer>
D	H01L 2924/10526	<no transfer>
D	H01L 2924/10527	<no transfer>
D	H01L 2924/10528	<no transfer>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2924/1057	<no transfer>
D	H01L 2924/10571	<no transfer>
D	H01L 2924/1062	<no transfer>
D	H01L 2924/10621	<no transfer>
D	H01L 2924/10622	<no transfer>
D	H01L 2924/10623	<no transfer>
D	H01L 2924/10624	<no transfer>
D	H01L 2924/10625	<no transfer>
D	H01L 2924/10626	<no transfer>
D	H01L 2924/1067	<no transfer>
D	H01L 2924/10671	<no transfer>
D	H01L 2924/10672	<no transfer>
D	H01L 2924/10673	<no transfer>
D	H01L 2924/10674	<no transfer>
D	H01L 2924/10675	<no transfer>
D	H01L 2924/10676	<no transfer>
D	H01L 2924/10677	<no transfer>
D	H01L 2924/10678	<no transfer>
D	H01L 2924/10679	<no transfer>
D	H01L 2924/1068	<no transfer>
D	H01L 2924/10681	<no transfer>
D	H01L 2924/1072	<no transfer>
D	H01L 2924/10721	<no transfer>
D	H01L 2924/10722	<no transfer>
D	H01L 2924/10723	<no transfer>
D	H01L 2924/10724	<no transfer>
D	H01L 2924/10725	<no transfer>
D	H01L 2924/1077	<no transfer>
D	H01L 2924/10771	<no transfer>
D	H01L 2924/10772	<no transfer>
D	H01L 2924/10773	<no transfer>
D	H01L 2924/10774	<no transfer>
D	H01L 2924/10775	<no transfer>
D	H01L 2924/10776	<no transfer>
D	H01L 2924/10777	<no transfer>
D	H01L 2924/10778	<no transfer>
D	H01L 2924/10779	<no transfer>
D	H01L 2924/1078	<no transfer>
D	H01L 2924/1082	<no transfer>
D	H01L 2924/10821	<no transfer>
D	H01L 2924/10822	<no transfer>
D	H01L 2924/10823	<no transfer>
D	H01L 2924/10824	<no transfer>
D	H01L 2924/10825	<no transfer>
D	H01L 2924/10826	<no transfer>
D	H01L 2924/10827	<no transfer>
D	H01L 2924/10828	<no transfer>
D	H01L 2924/10829	<no transfer>
D	H01L 2924/1083	<no transfer>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2924/10831	<no transfer>
D	H01L 2924/10832	<no transfer>
D	H01L 2924/10833	<no transfer>
D	H01L 2924/11	<no transfer>
D	H01L 2924/12	<no transfer>
D	H01L 2924/1203	<no transfer>
D	H01L 2924/12031	<no transfer>
D	H01L 2924/12032	<no transfer>
D	H01L 2924/12033	<no transfer>
D	H01L 2924/12034	<no transfer>
D	H01L 2924/12035	<no transfer>
D	H01L 2924/12036	<no transfer>
D	H01L 2924/12037	<no transfer>
D	H01L 2924/12038	<no transfer>
D	H01L 2924/1204	<no transfer>
D	H01L 2924/12041	<no transfer>
D	H01L 2924/12042	<no transfer>
D	H01L 2924/12043	<no transfer>
D	H01L 2924/12044	<no transfer>
D	H01L 2924/1205	<no transfer>
D	H01L 2924/1206	<no transfer>
D	H01L 2924/1207	<no transfer>
D	H01L 2924/13	<no transfer>
D	H01L 2924/1301	<no transfer>
D	H01L 2924/13011	<no transfer>
D	H01L 2924/13013	<no transfer>
D	H01L 2924/13014	<no transfer>
D	H01L 2924/13015	<no transfer>
D	H01L 2924/13016	<no transfer>
D	H01L 2924/13017	<no transfer>
D	H01L 2924/13018	<no transfer>
D	H01L 2924/13019	<no transfer>
D	H01L 2924/1302	<no transfer>
D	H01L 2924/13021	<no transfer>
D	H01L 2924/13022	<no transfer>
D	H01L 2924/13023	<no transfer>
D	H01L 2924/13024	<no transfer>
D	H01L 2924/13025	<no transfer>
D	H01L 2924/13026	<no transfer>
D	H01L 2924/13027	<no transfer>
D	H01L 2924/13028	<no transfer>
D	H01L 2924/13029	<no transfer>
D	H01L 2924/1303	<no transfer>
D	H01L 2924/13032	<no transfer>
D	H01L 2924/13033	<no transfer>
D	H01L 2924/13034	<no transfer>
D	H01L 2924/13035	<no transfer>
D	H01L 2924/1304	<no transfer>
D	H01L 2924/1305	<no transfer>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2924/13051	<no transfer>
D	H01L 2924/13052	<no transfer>
D	H01L 2924/13053	<no transfer>
D	H01L 2924/13054	<no transfer>
D	H01L 2924/13055	<no transfer>
D	H01L 2924/13056	<no transfer>
D	H01L 2924/1306	<no transfer>
D	H01L 2924/13061	<no transfer>
D	H01L 2924/13062	<no transfer>
D	H01L 2924/13063	<no transfer>
D	H01L 2924/13064	<no transfer>
D	H01L 2924/13066	<no transfer>
D	H01L 2924/13067	<no transfer>
D	H01L 2924/13068	<no transfer>
D	H01L 2924/13069	<no transfer>
D	H01L 2924/1307	<no transfer>
D	H01L 2924/13071	<no transfer>
D	H01L 2924/13072	<no transfer>
D	H01L 2924/13073	<no transfer>
D	H01L 2924/13074	<no transfer>
D	H01L 2924/13075	<no transfer>
D	H01L 2924/13076	<no transfer>
D	H01L 2924/13078	<no transfer>
D	H01L 2924/13079	<no transfer>
D	H01L 2924/1308	<no transfer>
D	H01L 2924/13081	<no transfer>
D	H01L 2924/13082	<no transfer>
D	H01L 2924/13083	<no transfer>
D	H01L 2924/13084	<no transfer>
D	H01L 2924/13085	<no transfer>
D	H01L 2924/13086	<no transfer>
D	H01L 2924/13087	<no transfer>
D	H01L 2924/13088	<no transfer>
D	H01L 2924/13089	<no transfer>
D	H01L 2924/1309	<no transfer>
D	H01L 2924/13091	<no transfer>
D	H01L 2924/13092	<no transfer>
D	H01L 2924/14	<no transfer>
D	H01L 2924/141	<no transfer>
D	H01L 2924/142	<no transfer>
D	H01L 2924/1421	<no transfer>
D	H01L 2924/14211	<no transfer>
D	H01L 2924/14215	<no transfer>
D	H01L 2924/1422	<no transfer>
D	H01L 2924/14221	<no transfer>
D	H01L 2924/14222	<no transfer>
D	H01L 2924/1423	<no transfer>
D	H01L 2924/1424	<no transfer>
D	H01L 2924/1425	<no transfer>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2924/14251	<no transfer>
D	H01L 2924/14252	<no transfer>
D	H01L 2924/14253	<no transfer>
D	H01L 2924/1426	<no transfer>
D	H01L 2924/1427	<no transfer>
D	H01L 2924/143	<no transfer>
D	H01L 2924/1431	<no transfer>
D	H01L 2924/1432	<no transfer>
D	H01L 2924/1433	<no transfer>
D	H01L 2924/14335	<no transfer>
D	H01L 2924/1434	<no transfer>
D	H01L 2924/1435	<no transfer>
D	H01L 2924/1436	<no transfer>
D	H01L 2924/14361	<no transfer>
D	H01L 2924/14362	<no transfer>
D	H01L 2924/14363	<no transfer>
D	H01L 2924/14364	<no transfer>
D	H01L 2924/14365	<no transfer>
D	H01L 2924/14366	<no transfer>
D	H01L 2924/14367	<no transfer>
D	H01L 2924/14368	<no transfer>
D	H01L 2924/14369	<no transfer>
D	H01L 2924/1437	<no transfer>
D	H01L 2924/1438	<no transfer>
D	H01L 2924/1441	<no transfer>
D	H01L 2924/1442	<no transfer>
D	H01L 2924/1443	<no transfer>
D	H01L 2924/1444	<no transfer>
D	H01L 2924/145	<no transfer>
D	H01L 2924/1451	<no transfer>
D	H01L 2924/14511	<no transfer>
D	H01L 2924/1453	<no transfer>
D	H01L 2924/146	<no transfer>
D	H01L 2924/1461	<no transfer>
D	H01L 2924/15	<no transfer>
D	H01L 2924/151	<administrative transfer to H10W 70/60>
D	H01L 2924/1511	<administrative transfer to H10W 70/60>
D	H01L 2924/1515	<administrative transfer to H10W 70/60>
D	H01L 2924/15151	<administrative transfer to H10W 70/681>
D	H01L 2924/15153	<administrative transfer to H10W 70/682>
D	H01L 2924/15155	<administrative transfer to H10W 70/682>
D	H01L 2924/15156	<administrative transfer to H10W 70/682>
D	H01L 2924/15157	<administrative transfer to H10W 70/682>
D	H01L 2924/15158	<no transfer>
D	H01L 2924/15159	<no transfer>
D	H01L 2924/15162	<no transfer>
D	H01L 2924/15165	<no transfer>
D	H01L 2924/1517	<administrative transfer to H10W 70/685>
D	H01L 2924/15172	<administrative transfer to H10W 70/655>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2924/15173	<administrative transfer to H10W 70/655>
D	H01L 2924/15174	<administrative transfer to H10W 70/655>
D	H01L 2924/15182	<administrative transfer to H10W 70/656>
D	H01L 2924/15183	<administrative transfer to H10W 70/656>
D	H01L 2924/15184	<administrative transfer to H10W 70/656>
D	H01L 2924/15192	<administrative transfer to H10W 70/63>
D	H01L 2924/152	<no transfer>
D	H01L 2924/153	<no transfer>
D	H01L 2924/1531	<no transfer>
D	H01L 2924/15311	<no transfer>
D	H01L 2924/15312	<no transfer>
D	H01L 2924/15313	<no transfer>
D	H01L 2924/1532	<no transfer>
D	H01L 2924/15321	<no transfer>
D	H01L 2924/15322	<no transfer>
D	H01L 2924/15323	<no transfer>
D	H01L 2924/1533	<no transfer>
D	H01L 2924/15331	<no transfer>
D	H01L 2924/15332	<no transfer>
D	H01L 2924/15333	<no transfer>
D	H01L 2924/156	<no transfer>
D	H01L 2924/157	<no transfer>
D	H01L 2924/15701	<no transfer>
D	H01L 2924/15717	<no transfer>
D	H01L 2924/15724	<no transfer>
D	H01L 2924/15738	<no transfer>
D	H01L 2924/15747	<no transfer>
D	H01L 2924/1576	<no transfer>
D	H01L 2924/15763	<no transfer>
D	H01L 2924/15786	<no transfer>
D	H01L 2924/15787	<no transfer>
D	H01L 2924/15788	<no transfer>
D	H01L 2924/1579	<no transfer>
D	H01L 2924/15791	<no transfer>
D	H01L 2924/15793	<no transfer>
D	H01L 2924/15798	<no transfer>
D	H01L 2924/161	<administrative transfer to H10W 76/10>
D	H01L 2924/1611	<administrative transfer to H10W 76/10>
D	H01L 2924/1615	<administrative transfer to H10W 76/12>
D	H01L 2924/16151	<no transfer>
D	H01L 2924/16152	<no transfer>
D	H01L 2924/16153	<no transfer>
D	H01L 2924/1616	<no transfer>
D	H01L 2924/1617	<no transfer>
D	H01L 2924/16171	<no transfer>
D	H01L 2924/16172	<no transfer>
D	H01L 2924/16173	<no transfer>
D	H01L 2924/16174	<no transfer>
D	H01L 2924/16175	<no transfer>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2924/16176	<no transfer>
D	H01L 2924/16177	<no transfer>
D	H01L 2924/16178	<no transfer>
D	H01L 2924/16179	<no transfer>
D	H01L 2924/1619	<no transfer>
D	H01L 2924/16195	<no transfer>
D	H01L 2924/16196	<no transfer>
D	H01L 2924/162	<no transfer>
D	H01L 2924/16235	<no transfer>
D	H01L 2924/16251	<no transfer>
D	H01L 2924/1626	<no transfer>
D	H01L 2924/1627	<no transfer>
D	H01L 2924/163	<administrative transfer to H10W 76/60>
D	H01L 2924/1631	<administrative transfer to H10W 76/60>
D	H01L 2924/16315	<administrative transfer to H10W 76/63>
D	H01L 2924/1632	<administrative transfer to H10W 76/63>
D	H01L 2924/164	<administrative transfer to H10W 76/67>
D	H01L 2924/165	<administrative transfer to H10W 76/67>
D	H01L 2924/16586	<administrative transfer to H10W 76/67>
D	H01L 2924/16587	<administrative transfer to H10W 76/67>
D	H01L 2924/16588	<administrative transfer to H10W 76/67>
D	H01L 2924/1659	<administrative transfer to H10W 76/67>
D	H01L 2924/16593	<administrative transfer to H10W 76/67>
D	H01L 2924/16598	<administrative transfer to H10W 76/67>
D	H01L 2924/166	<administrative transfer to H10W 76/17>
D	H01L 2924/167	<administrative transfer to H10W 76/17>
D	H01L 2924/16701	<administrative transfer to H10W 76/17>
D	H01L 2924/16717	<administrative transfer to H10W 76/17>
D	H01L 2924/16724	<administrative transfer to H10W 76/17>
D	H01L 2924/16738	<administrative transfer to H10W 76/17>
D	H01L 2924/16747	<administrative transfer to H10W 76/17>
D	H01L 2924/1676	<administrative transfer to H10W 76/17>
D	H01L 2924/16763	<administrative transfer to H10W 76/17>
D	H01L 2924/16786	<administrative transfer to H10W 76/18>
D	H01L 2924/16787	<administrative transfer to H10W 76/18>
D	H01L 2924/16788	<administrative transfer to H10W 76/18>
D	H01L 2924/1679	<administrative transfer to H10W 76/18>
D	H01L 2924/16791	<administrative transfer to H10W 76/18>
D	H01L 2924/16793	<no transfer>
D	H01L 2924/16798	<no transfer>
D	H01L 2924/171	<administrative transfer to H10W 76/10>
D	H01L 2924/1711	<administrative transfer to H10W 76/10>
D	H01L 2924/1715	<administrative transfer to H10W 76/12>
D	H01L 2924/17151	<administrative transfer to H10W 76/167>
D	H01L 2924/172	<administrative transfer to H10W 76/10>
D	H01L 2924/173	<administrative transfer to H10W 76/60>
D	H01L 2924/176	<administrative transfer to H10W 76/17>
D	H01L 2924/177	<administrative transfer to H10W 76/17>
D	H01L 2924/17701	<administrative transfer to H10W 76/17>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2924/17717	<administrative transfer to H10W 76/17>
D	H01L 2924/17724	<administrative transfer to H10W 76/17>
D	H01L 2924/17738	<administrative transfer to H10W 76/17>
D	H01L 2924/17747	<administrative transfer to H10W 76/17>
D	H01L 2924/1776	<administrative transfer to H10W 76/17>
D	H01L 2924/17763	<administrative transfer to H10W 76/17>
D	H01L 2924/17786	<administrative transfer to H10W 76/17>
D	H01L 2924/17787	<administrative transfer to H10W 76/17>
D	H01L 2924/17788	<administrative transfer to H10W 76/17>
D	H01L 2924/1779	<administrative transfer to H10W 76/17>
D	H01L 2924/17791	<administrative transfer to H10W 76/17>
D	H01L 2924/17793	<administrative transfer to H10W 76/17>
D	H01L 2924/17798	<administrative transfer to H10W 76/17>
D	H01L 2924/181	<administrative transfer to H10W 74/00>
D	H01L 2924/1811	<administrative transfer to H10W 74/00>
D	H01L 2924/1815	<administrative transfer to H10W 74/10>
D	H01L 2924/1816	<administrative transfer to H10W 74/142>
D	H01L 2924/18161	<administrative transfer to H10W 74/142>
D	H01L 2924/18162	<administrative transfer to H10W 74/142>
D	H01L 2924/18165	<administrative transfer to H10W 74/142>
D	H01L 2924/182	<administrative transfer to H10W 74/00>
D	H01L 2924/183	<administrative transfer to H10W 74/127>
D	H01L 2924/18301	<administrative transfer to H10W 74/127>
D	H01L 2924/186	<administrative transfer to H10W 74/40>
D	H01L 2924/19	<no transfer>
D	H01L 2924/1901	<no transfer>
D	H01L 2924/19011	<no transfer>
D	H01L 2924/19015	<no transfer>
D	H01L 2924/1902	<no transfer>
D	H01L 2924/1903	<no transfer>
D	H01L 2924/19031	<no transfer>
D	H01L 2924/19032	<no transfer>
D	H01L 2924/19033	<no transfer>
D	H01L 2924/19038	<no transfer>
D	H01L 2924/19039	<no transfer>
D	H01L 2924/1904	<no transfer>
D	H01L 2924/19041	<no transfer>
D	H01L 2924/19042	<no transfer>
D	H01L 2924/19043	<no transfer>
D	H01L 2924/1905	<no transfer>
D	H01L 2924/19051	<no transfer>
D	H01L 2924/191	<no transfer>
D	H01L 2924/19101	<no transfer>
D	H01L 2924/19102	<no transfer>
D	H01L 2924/19103	<no transfer>
D	H01L 2924/19104	<no transfer>
D	H01L 2924/19105	<no transfer>
D	H01L 2924/19106	<no transfer>
D	H01L 2924/19107	<no transfer>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2924/20	<no transfer>
D	H01L 2924/201	<no transfer>
D	H01L 2924/20101	<no transfer>
D	H01L 2924/20102	<no transfer>
D	H01L 2924/20103	<no transfer>
D	H01L 2924/20104	<no transfer>
D	H01L 2924/20105	<no transfer>
D	H01L 2924/20106	<no transfer>
D	H01L 2924/20107	<no transfer>
D	H01L 2924/20108	<no transfer>
D	H01L 2924/20109	<no transfer>
D	H01L 2924/2011	<no transfer>
D	H01L 2924/20111	<no transfer>
D	H01L 2924/202	<no transfer>
D	H01L 2924/20201	<no transfer>
D	H01L 2924/20202	<no transfer>
D	H01L 2924/2021	<no transfer>
D	H01L 2924/20211	<no transfer>
D	H01L 2924/20212	<no transfer>
D	H01L 2924/20213	<no transfer>
D	H01L 2924/2024	<no transfer>
D	H01L 2924/2026	<no transfer>
D	H01L 2924/20261	<no transfer>
D	H01L 2924/20262	<no transfer>
D	H01L 2924/20263	<no transfer>
D	H01L 2924/2027	<no transfer>
D	H01L 2924/20271	<no transfer>
D	H01L 2924/203	<no transfer>
D	H01L 2924/20301	<no transfer>
D	H01L 2924/20302	<no transfer>
D	H01L 2924/20303	<no transfer>
D	H01L 2924/20304	<no transfer>
D	H01L 2924/20305	<no transfer>
D	H01L 2924/20306	<no transfer>
D	H01L 2924/20307	<no transfer>
D	H01L 2924/20308	<no transfer>
D	H01L 2924/20309	<no transfer>
D	H01L 2924/206	<no transfer>
D	H01L 2924/2064	<no transfer>
D	H01L 2924/20641	<no transfer>
D	H01L 2924/20642	<no transfer>
D	H01L 2924/20643	<no transfer>
D	H01L 2924/20644	<no transfer>
D	H01L 2924/20645	<no transfer>
D	H01L 2924/20646	<no transfer>
D	H01L 2924/20647	<no transfer>
D	H01L 2924/20648	<no transfer>
D	H01L 2924/20649	<no transfer>
D	H01L 2924/2065	<no transfer>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2924/20651	<no transfer>
D	H01L 2924/20652	<no transfer>
D	H01L 2924/20653	<no transfer>
D	H01L 2924/20654	<no transfer>
D	H01L 2924/20655	<no transfer>
D	H01L 2924/20656	<no transfer>
D	H01L 2924/20657	<no transfer>
D	H01L 2924/20658	<no transfer>
D	H01L 2924/207	<no transfer>
D	H01L 2924/2075	<no transfer>
D	H01L 2924/20751	<no transfer>
D	H01L 2924/20752	<no transfer>
D	H01L 2924/20753	<no transfer>
D	H01L 2924/20754	<no transfer>
D	H01L 2924/20755	<no transfer>
D	H01L 2924/20756	<no transfer>
D	H01L 2924/20757	<no transfer>
D	H01L 2924/20758	<no transfer>
D	H01L 2924/20759	<no transfer>
D	H01L 2924/2076	<no transfer>
D	H01L 2924/30	<no transfer>
D	H01L 2924/301	<no transfer>
D	H01L 2924/30101	<no transfer>
D	H01L 2924/30105	<no transfer>
D	H01L 2924/30107	<no transfer>
D	H01L 2924/3011	<no transfer>
D	H01L 2924/30111	<no transfer>
D	H01L 2924/302	<no transfer>
D	H01L 2924/30201	<no transfer>
D	H01L 2924/30205	<no transfer>
D	H01L 2924/3025	<no transfer>
D	H01L 2924/35	<no transfer>
D	H01L 2924/351	<no transfer>
D	H01L 2924/3511	<no transfer>
D	H01L 2924/3512	<no transfer>
D	H01L 2924/35121	<no transfer>
D	H01L 2924/36	<no transfer>
D	H01L 2924/364	<no transfer>
D	H01L 2924/3641	<no transfer>
D	H01L 2924/365	<no transfer>
D	H01L 2924/3651	<administrative transfer to H10W 95/00>
D	H01L 2924/36511	<administrative transfer to H10W 95/00>
D	H01L 2924/3656	<administrative transfer to H10W 95/00>
D	H01L 2924/37	<no transfer>
D	H01L 2924/37001	<no transfer>
D	H01L 2924/37002	<no transfer>
D	H01L 2924/3701	<no transfer>
D	H01L 2924/38	<no transfer>
D	H01L 2924/381	<no transfer>

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
D	H01L 2924/384	<no transfer>
D	H01L 2924/3841	<no transfer>
D	H01L 2924/386	<no transfer>
D	H01L 2924/3861	<no transfer>
D	H01L 2924/3862	<no transfer>
D	H01L 2924/40	<no transfer>
D	H01L 2924/401	<no transfer>
D	H01L 2924/40101	<no transfer>
D	H01L 2924/40102	<no transfer>
D	H01L 2924/40103	<no transfer>
D	H01L 2924/40105	<no transfer>
D	H01L 2924/4015	<no transfer>
D	H01L 2924/402	<no transfer>
D	H01L 2924/40201	<no transfer>
D	H01L 2924/40202	<no transfer>
D	H01L 2924/40203	<no transfer>
D	H01L 2924/40207	<no transfer>
D	H01L 2924/4025	<no transfer>
D	H01L 2924/40251	<no transfer>
D	H01L 2924/40252	<no transfer>
D	H01L 2924/40253	<no transfer>
D	H01L 2924/40254	<no transfer>
D	H01L 2924/40255	<no transfer>
D	H01L 2924/403	<no transfer>
D	H01L 2924/40301	<no transfer>
D	H01L 2924/40302	<no transfer>
D	H01L 2924/40303	<no transfer>
D	H01L 2924/40304	<no transfer>
D	H01L 2924/40305	<no transfer>
D	H01L 2924/40306	<no transfer>
D	H01L 2924/4035	<no transfer>
D	H01L 2924/404	<no transfer>
D	H01L 2924/40401	<no transfer>
D	H01L 2924/40402	<no transfer>
D	H01L 2924/40403	<no transfer>
D	H01L 2924/40404	<no transfer>
D	H01L 2924/40405	<no transfer>
D	H01L 2924/40406	<no transfer>
D	H01L 2924/40407	<no transfer>
D	H01L 2924/405	<no transfer>
D	H01L 2924/40501	<no transfer>
D	H01L 2924/40502	<no transfer>
D	H01L 2924/40503	<no transfer>
Q	H10W 20/023	H10W 20/023, H10W 20/0234, H10W 20/0238, H10W 20/0242, H10W 20/0245, H10W 20/0249, H10W 20/0253, H10W 20/0257, H10W 20/0261, H10W 20/0265
Q	H10W 20/037	H10W 20/037, H10W 20/0372
Q	H10W 20/056	H10W 20/056, H10W 20/0595
Q	H10W 20/063	H10W 20/063, H10W 20/0633, H10W 20/0636

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
Q	H10W 20/069	H10W 20/069, H10W 20/0693, H10W 20/0696
Q	H10W 20/20	H10W 20/20, H10W 20/211, H10W 20/212, H10W 20/2125, H10W 20/2128, H10W 20/213, H10W 20/2134, H10W 20/215, H10W 20/216, H10W 20/217, H10W 20/218, H10W 20/222, H10W 20/233
Q	H10W 20/40	H10W 20/40, H10W 20/41, H10W 20/42, H10W 20/421, H10W 20/422, H10W 20/423, H10W 20/425, H10W 20/427, H10W 20/43, H10W 20/432, H10W 20/435, H10W 20/438, H10W 20/44, H10W 20/4403, H10W 20/4405, H10W 20/4407, H10W 20/4421, H10W 20/4424, H10W 20/4432, H10W 20/4435, H10W 20/4441, H10W 20/4446, H10W 20/4451, H10W 20/4462, H10W 20/4473, H10W 20/4484, H10W 20/45, H10W 20/455, H10W 20/46, H10W 20/47, H10W 20/48, H10W 20/481, H10W 20/482, H10W 70/60, H10W 70/611, H10W 70/614, H10W 70/616, H10W 70/62, H10W 70/63, H10W 70/635, H10W 70/641, H10W 70/644, H10W 70/65, H10W 70/652, H10W 70/6523, H10W 70/6525, H10W 70/6528, H10W 70/654, H10W 70/655, H10W 70/656, H10W 70/657, H10W 70/658, H10W 70/66, H10W 70/662, H10W 70/664, H10W 70/666, H10W 70/668, H10W 70/67, H10W 70/68, H10W 70/681, H10W 70/682, H10W 70/685, H10W 70/688, H10W 70/69, H10W 70/692, H10W 70/695, H10W 70/698, H10W 72/00
Q	H10W 20/42	H10W 20/42, H10W 20/421, H10W 20/422
Q	H10W 20/425	H10W 20/425, H10W 20/455
Q	H10W 20/4403	H10W 20/4403, H10W 20/4437
Q	H10W 40/00	H10W 40/00, H10W 40/20, H10W 40/50
Q	H10W 40/22	H10W 40/22, H10W 40/226, H10W 40/228, H10W 40/231, H10W 40/233, H10W 40/235, H10W 40/237, H10W 40/242
Q	H10W 42/00	H10W 42/00, H10W 42/101, H10W 40/80, H10W 99/00
Q	H10W 42/20	H10W 42/20, H10W 42/40, H10W 42/261, H10W 42/263, H10W 42/265, H10W 42/267, H10W 42/271, H10W 42/273, H10W 42/276, H10W 42/281, H10W 42/284, H10W 42/287
Q	H10W 70/02	H10W 70/02, H10W 40/03
Q	H10W 70/027	H10W 40/033, H10W 70/027
Q	H10W 70/05	H10W 70/05, H10W 70/06, H10W 70/08, H10W 70/09, H10W 70/092, H10W 70/093, H10W 70/095, H10W 70/096, H10W 70/097, H10W 70/098
Q	H10W 70/60	H10W 70/60, H10W 70/611, H10W 70/614, H10W 70/616, H10W 70/618, H10W 70/62, H10W 70/63, H10W 70/635, H10W 70/641, H10W 70/644, H10W 70/65, H10W 70/652, H10W 70/6523, H10W 70/6525, H10W 70/6528, H10W 70/654, H10W 70/655, H10W 70/656, H10W 70/6565, H10W 70/657, H10W 70/658, H10W 70/66, H10W 70/662, H10W 70/664, H10W 70/666, H10W 70/668, H10W 70/67, H10W 70/68, H10W 70/681, H10W 70/682, H10W 70/685, H10W 70/686, H10W 70/687, H10W 70/69, H10W 70/692, H10W 70/695, H10W 70/698, H10W 70/699
Q	H10W 70/65	H10W 70/65, H10W 70/652, H10W 70/6523, H10W 70/6525, H10W 70/6528, H10W 70/654, H10W 70/655, H10W 70/656, H10W 70/6565, H10W 70/657, H10W 70/658

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
Q	H10W 70/66	H10W 70/66, H10W 70/662, H10W 70/664, H10W 70/666, H10W 70/668
Q	H10W 70/685	H10W 70/685, H10W 70/686, H10W 70/687
Q	H10W 70/69	H10W 70/69, H10W 70/692, H10W 70/695, H10W 70/698, H10W 70/686
Q	H10W 72/00	H10W 72/00, H10W 72/20, H10W 72/221, H10W 72/222, H10W 72/223, H10W 72/224, H10W 72/225, H10W 72/227, H10W 72/228, H10W 72/231, H10W 72/232, H10W 72/234, H10W 72/235, H10W 72/237, H10W 72/241, H10W 72/242, H10W 72/244, H10W 72/245, H10W 72/247, H10W 72/248, H10W 72/251, H10W 72/252, H10W 72/253, H10W 72/255, H10W 72/257, H10W 72/2524, H10W 72/2528, H10W 72/261, H10W 72/263, H10W 72/265, H10W 72/267, H10W 72/281, H10W 72/283, H10W 72/285, H10W 72/287, H10W 72/30, H10W 72/321, H10W 72/322, H10W 72/323, H10W 72/324, H10W 72/325, H10W 72/327, H10W 72/328, H10W 72/331, H10W 72/332, H10W 72/334, H10W 72/335, H10W 72/337, H10W 72/341, H10W 72/342, H10W 72/344, H10W 72/345, H10W 72/347, H10W 72/348, H10W 72/351, H10W 72/352, H10W 72/353, H10W 72/354, H10W 72/355, H10W 72/357, H10W 72/3524, H10W 72/3528, H10W 72/361, H10W 72/365, H10W 72/367, H10W 72/381, H10W 72/383, H10W 72/385, H10W 72/387, H10W 72/40, H10W 72/49, H10W 72/50, H10W 72/521, H10W 72/522, H10W 72/523, H10W 72/524, H10W 72/525, H10W 72/527, H10W 72/528, H10W 72/531, H10W 72/533, H10W 72/534, H10W 72/535, H10W 72/537, H10W 72/536, H10W 72/5363, H10W 72/5366, H10W 72/5368, H10W 72/541, H10W 72/543, H10W 72/547, H10W 72/5434, H10W 72/5438, H10W 72/5473, H10W 72/5475, H10W 72/5445, H10W 72/5449, H10W 72/5453, H10W 72/551, H10W 72/552, H10W 72/5522, H10W 72/5524, H10W 72/5525, H10W 72/553, H10W 72/555, H10W 72/557, H10W 72/5528, H10W 72/581, H10W 72/583, H10W 72/585, H10W 72/60, H10W 72/621, H10W 72/622, H10W 72/623, H10W 72/624, H10W 72/625, H10W 72/627, H10W 72/631, H10W 72/634, H10W 72/635, H10W 72/637, H10W 72/641, H10W 72/645, H10W 72/647, H10W 72/646, H10W 72/642, H10W 72/643, H10W 72/6478, H10W 72/651, H10W 72/652, H10W 72/653, H10W 72/6528, H10W 72/655, H10W 72/657, H10W 72/681, H10W 72/683, H10W 72/685, H10W 72/691

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
Q	H10W 72/01	H10W 72/01, H10W 72/011, H10W 72/0112, H10W 72/0113, H10W 72/0115, H10W 72/0116, H10W 72/012, H10W 72/01204, H10W 72/01208, H10W 72/01212, H10W 72/01215, H10W 72/01221, H10W 72/01223, H10W 72/01225, H10W 72/01231, H10W 72/01233, H10W 72/01235, H10W 72/01236, H10W 72/01238, H10W 72/01251, H10W 72/01253, H10W 72/01255, H10W 72/01257, H10W 72/01261, H10W 72/01265, H10W 72/01271, H10W 72/013, H10W 72/01304, H10W 72/01308, H10W 72/01315, H10W 72/01321, H10W 72/01323, H10W 72/01325, H10W 72/01331, H10W 72/01333, H10W 72/01335, H10W 72/01336, H10W 72/01338, H10W 72/01351, H10W 72/01353, H10W 72/01355, H10W 72/01357, H10W 72/01359, H10W 72/01361, H10W 72/01365, H10W 72/01371, H10W 72/014, H10W 72/015, H10W 72/01504, H10W 72/01515, H10W 72/01551, H10W 72/01553, H10W 72/01561, H10W 72/01565, H10W 72/01571, H10W 72/016, H10W 72/01604, H10W 72/01615, H10W 72/01651, H10W 72/01653, H10W 72/01661, H10W 72/01665, H10W 72/01671, H10W 72/019, H10W 72/01904, H10W 72/01908, H10W 72/01921, H10W 72/01923, H10W 72/01925, H10W 72/01931, H10W 72/01933, H10W 72/01935, H10W 72/01936, H10W 72/01938, H10W 72/01951, H10W 72/01953, H10W 72/01955, H10W 72/01961, H10W 72/01971, H10W 72/0198
Q	H10W 72/012	H10W 72/012, H10W 72/01204, H10W 72/01208, H10W 72/01212, H10W 72/01215, H10W 72/01221, H10W 72/01223, H10W 72/01225, H10W 72/01231, H10W 72/01233, H10W 72/01235, H10W 72/01236, H10W 72/01238, H10W 72/01251, H10W 72/01253, H10W 72/01255, H10W 72/01257, H10W 72/01261, H10W 72/01265, H10W 72/01271
Q	H10W 72/013	H10W 72/013, H10W 72/01304, H10W 72/01308, H10W 72/01315, H10W 72/01321, H10W 72/01323, H10W 72/01325, H10W 72/01331, H10W 72/01333, H10W 72/01335, H10W 72/01336, H10W 72/01338, H10W 72/01351, H10W 72/01353, H10W 72/01355, H10W 72/01357, H10W 72/01359, H10W 72/01361, H10W 72/01365, H10W 72/01371
Q	H10W 72/015	H10W 72/015, H10W 72/01504, H10W 72/01515, H10W 72/01551, H10W 72/01553, H10W 72/01561, H10W 72/01565, H10W 72/01571
Q	H10W 72/016	H10W 72/016, H10W 72/01604, H10W 72/01615, H10W 72/01651, H10W 72/01653, H10W 72/01661, H10W 72/01665, H10W 72/01671
Q	H10W 72/019	H10W 72/019, H10W 72/01904, H10W 72/01908, H10W 72/01921, H10W 72/01923, H10W 72/01925, H10W 72/01931, H10W 72/01933, H10W 72/01935, H10W 72/01936, H10W 72/01938, H10W 72/01951, H10W 72/01953, H10W 72/01955, H10W 72/01961, H10W 72/01971
Q	H10W 72/07204	H10W 72/07204, H10W 72/07207
Q	H10W 72/07232	H10W 72/00, H10W 72/07232, H10W 72/07332, H10W 72/07532, H10W 72/07632, H10W 95/00
Q	H10W 72/07233	H10W 72/00, H10W 72/07233, H10W 72/07333, H10W 72/07533, H10W 72/07633, H10W 95/00
Q	H10W 72/07236	H10W 72/00, H10W 72/07236, H10W 72/07336, H10W 72/07536, H10W 72/07636, H10W 95/00

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Type*	<u>From CPC Symbol (existing)</u>	<u>To CPC Symbol(s)</u>
Q	H10W 72/20	H10W 72/20, H10W 72/221, H10W 72/222, H10W 72/223, H10W 72/224, H10W 72/225, H10W 72/227, H10W 72/228, H10W 72/231, H10W 72/232, H10W 72/234, H10W 72/235, H10W 72/237, H10W 72/241, H10W 72/242, H10W 72/244, H10W 72/245, H10W 72/247, H10W 72/248, H10W 72/251, H10W 72/252, H10W 72/253, H10W 72/255, H10W 72/257, H10W 72/2524, H10W 72/2528, H10W 72/261, H10W 72/263, H10W 72/265, H10W 72/267, H10W 72/281, H10W 72/283, H10W 72/285, H10W 72/287, H10W 72/60, H10W 72/621, H10W 72/622, H10W 72/623, H10W 72/624, H10W 72/625, H10W 72/627, H10W 72/631, H10W 72/634, H10W 72/635, H10W 72/637, H10W 72/641, H10W 72/645, H10W 72/647, H10W 72/642, H10W 72/643, H10W 72/646, H10W 72/6478, H10W 72/651, H10W 72/652, H10W 72/653, H10W 72/6528, H10W 72/655, H10W 72/657, H10W 72/681, H10W 72/683, H10W 72/685, H10W 72/691
Q	H10W 72/30	H10W 72/014, H10W 72/074, H10W 72/30, H10W 72/321, H10W 72/322, H10W 72/323, H10W 72/324, H10W 72/325, H10W 72/327, H10W 72/328, H10W 72/331, H10W 72/332, H10W 72/334, H10W 72/335, H10W 72/337, H10W 72/341, H10W 72/342, H10W 72/344, H10W 72/345, H10W 72/347, H10W 72/348, H10W 72/351, H10W 72/352, H10W 72/353, H10W 72/354, H10W 72/355, H10W 72/357, H10W 72/3524, H10W 72/3528, H10W 72/361, H10W 72/365, H10W 72/367, H10W 72/381, H10W 72/383, H10W 72/385, H10W 72/387, H10W 72/40, H10W 72/49
Q	H10W 72/50	H10W 72/50, H10W 72/521, H10W 72/522, H10W 72/523, H10W 72/524, H10W 72/525, H10W 72/527, H10W 72/528, H10W 72/531, H10W 72/533, H10W 72/534, H10W 72/535, H10W 72/537, H10W 72/536, H10W 72/5363, H10W 72/5366, H10W 72/5368, H10W 72/541, H10W 72/543, H10W 72/547, H10W 72/5434, H10W 72/5438, H10W 72/5473, H10W 72/5475, H10W 72/5445, H10W 72/5449, H10W 72/5453, H10W 72/551, H10W 72/552, H10W 72/5522, H10W 72/5524, H10W 72/5525, H10W 72/553, H10W 72/555, H10W 72/557, H10W 72/5528, H10W 72/581, H10W 72/583, H10W 72/585
Q	H10W 72/60	H10W 72/60, H10W 72/621, H10W 72/622, H10W 72/623, H10W 72/624, H10W 72/625, H10W 72/627, H10W 72/631, H10W 72/634, H10W 72/635, H10W 72/637, H10W 72/641, H10W 72/645, H10W 72/647, H10W 72/646, H10W 72/642, H10W 72/643, H10W 72/6478, H10W 72/651, H10W 72/652, H10W 72/653, H10W 72/6528, H10W 72/655, H10W 72/657, H10W 72/681, H10W 72/683, H10W 72/685, H10W 72/701
Q	H10W 72/801	H10W 72/801, H10W 72/812
Q	H10W 72/823	H10W 20/20, H10W 20/211, H10W 20/215, H10W 20/222, H10W 72/823, H10W 76/132, H10W 76/134, H10W 76/153, H10W 76/157, H10W 76/165

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Type*	From CPC Symbol (existing)	To CPC Symbol(s)
Q	H10W 72/90	H10W 72/90, H10W 72/921, H10W 72/922, H10W 72/9223, H10W 72/9226, H10W 72/923, H10W 72/9232, H10W 72/924, H10W 72/925, H10W 72/926, H10W 72/927, H10W 72/931, H10W 72/932, H10W 72/934, H10W 72/936, H10W 72/941, H10W 72/9413, H10W 72/9415, H10W 72/942, H10W 72/944, H10W 72/9445, H10W 72/951, H10W 72/952, H10W 72/953, H10W 72/957, H10W 72/9524, H10W 72/9528, H10W 72/961, H10W 72/963, H10W 72/965, H10W 72/967, H10W 72/981, H10W 72/983, H10W 72/985, H10W 72/987
Q	H10W 74/10	H10W 74/10, H10W 74/15
Q	H10W 76/60	H10W 76/60, H10W 76/63, H10W 76/67
Q	H10W 90/00	H10B 80/00, H10D 80/00, H10D 80/20, H10D 80/211, H10D 80/213, H10D 80/215, H10D 80/231, H10D 80/251, H10D 80/30, H10F 39/90, H10F 39/95, H10H 29/20, H10H 29/24, H10H 29/30, H10H 29/32, H10H 29/34, H10H 29/345, H10H 29/352, H10H 29/362, H10H 29/37, H10H 29/39, H10H 29/41, H10H 29/45, H10H 29/49, H10K 19/00, H10K 19/10, H10K 19/20, H10K 19/201, H10K 19/202, H10K 19/80, H10K 19/901, H10K 39/601, H10K 39/621, H10K 59/90, H10K 59/95, H10K 65/00, H10W 90/00, H10W 90/10, H10W 90/15, H10W 90/155, H10W 90/20, H10W 90/22, H10W 90/231, H10W 90/24, H10W 90/26, H10W 90/271, H10W 90/275, H10W 90/28, H10W 90/284, H10W 90/288, H10W 90/291, H10W 90/293, H10W 90/295, H10W 90/701, H10W 90/721, H10W 90/722, H10W 90/723, H10W 90/724, H10W 90/725, H10W 90/726, H10W 90/727, H10W 90/728, H10W 90/729, H10W 90/731, H10W 90/732, H10W 90/733, H10W 90/734, H10W 90/735, H10W 90/736, H10W 90/737, H10W 90/738, H10W 90/739, H10W 90/751, H10W 90/752, H10W 90/753, H10W 90/754, H10W 90/755, H10W 90/756, H10W 90/757, H10W 90/758, H10W 90/759, H10W 90/761, H10W 90/762, H10W 90/763, H10W 90/764, H10W 90/765, H10W 90/766, H10W 90/767, H10W 90/768, H10W 90/769, H10W 90/791, H10W 90/792, H10W 90/794, H10W 90/796, H10W 90/798, H10W 90/811
Q	H10W 90/701	H10W 90/701, H10W 90/724, H10W 90/725, H10W 90/7295, H10W 90/754, H10W 90/755, H10W 90/764, H10W 90/765
Q	H10W 90/724	H10W 90/724, H10W 90/726
Q	H10W 90/754	H10W 90/754, H10W 90/756
Q	H10W 99/00	H10W 40/00, H10W 40/01, H10W 42/00, H10W 70/00, H10W 70/01, H10W 70/02, H10W 70/04, H10W 70/05, H10W 70/06, H10W 70/08, H10W 70/09, H10W 74/01, H10W 76/01, H10W 95/00, H10W 99/00

* C = entries with modified file scope where reclassification of documents from the entries is involved; Q = new entries which are firstly populated with documents via administrative transfers from deleted (D) entries. Afterwards, the transferred documents into the Q entry will either stay or be moved to more appropriate entries, as determined by intellectual reclassification; D = deleted entries; F = frozen entries will be deleted once reclassification of documents from the entries is completed.

NOTES:

- Only C, D, F, and Q type entries are included in the table above.
- When multiple symbols are included in the “To” column, do not use ranges of symbols.
- For administrative transfer of documents, the following text should be used: “< administrative transfer to XX>”, “<administrative transfer to XX and YY simultaneously>”, or “<administrative transfer to XX, YY, ...and ZZ simultaneously>” when administrative transfer of the same documents is to more than one place.

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- Administrative transfer to main trunk groups is assumed to be the source allocation type, unless otherwise indicated.
- Administrative transfer to 2000/Y series groups is assumed to be “additional information”.
- If needed, instructions for allocation type should be indicated within the angle brackets using the abbreviations “ADD” or “INV”: <administrative transfer to XX ADD>, <administrative transfer to XX INV>, or < administrative transfer to XX ADD, YY INV, ... and ZZ ADD simultaneously>.
- In certain situations, the “D” entries of 2000-series or Y-series groups may not require a destination (“To”) symbol, however it is required to specify “<no transfer>” in the “To” column for such cases.
- RCL is not needed for finalisation projects.

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4. CHANGES TO THE CPC-TO-IPC CONCORDANCE LIST (CICL)

<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 21/48		DELETE
H01L 21/4803		DELETE
H01L 21/4807		DELETE
H01L 21/481		DELETE
H01L 21/4814		DELETE
H01L 21/4817		DELETE
H01L 21/4821		DELETE
H01L 21/4825		DELETE
H01L 21/4828		DELETE
H01L 21/4832		DELETE
H01L 21/4835		DELETE
H01L 21/4839		DELETE
H01L 21/4842		DELETE
H01L 21/4846		DELETE
H01L 21/485		DELETE
H01L 21/4853		DELETE
H01L 21/4857		DELETE
H01L 21/486		DELETE
H01L 21/4864		DELETE
H01L 21/4867		DELETE
H01L 21/4871		DELETE
H01L 21/4875		DELETE
H01L 21/4878		DELETE
H01L 21/4882		DELETE
H01L 21/4885		DELETE
H01L 21/4889		DELETE
H01L 21/4892		DELETE
H01L 21/4896		DELETE
H01L 21/50		DELETE
H01L 21/52		DELETE
H01L 21/54		DELETE
H01L 21/56		DELETE
H01L 21/561		DELETE
H01L 21/563		DELETE
H01L 21/565		DELETE
H01L 21/566		DELETE
H01L 21/568		DELETE
H01L 21/60		DELETE
H01L 2021/60007		DELETE
H01L 2021/60015		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2021/60022		DELETE
H01L 2021/6003		DELETE
H01L 2021/60037		DELETE
H01L 2021/60045		DELETE
H01L 2021/60052		DELETE
H01L 2021/6006		DELETE
H01L 2021/60067		DELETE
H01L 2021/60075		DELETE
H01L 2021/60082		DELETE
H01L 2021/6009		DELETE
H01L 2021/60097		DELETE
H01L 2021/60105		DELETE
H01L 2021/60112		DELETE
H01L 2021/6012		DELETE
H01L 2021/60127		DELETE
H01L 2021/60135		DELETE
H01L 2021/60142		DELETE
H01L 2021/6015		DELETE
H01L 2021/60157		DELETE
H01L 2021/60165		DELETE
H01L 2021/60172		DELETE
H01L 2021/6018		DELETE
H01L 2021/60187		DELETE
H01L 2021/60195		DELETE
H01L 2021/60202		DELETE
H01L 2021/6021		DELETE
H01L 2021/60217		DELETE
H01L 2021/60225		DELETE
H01L 2021/60232		DELETE
H01L 2021/6024		DELETE
H01L 2021/60247		DELETE
H01L 2021/60255		DELETE
H01L 2021/60262		DELETE
H01L 2021/6027		DELETE
H01L 2021/60277		DELETE
H01L 2021/60285		DELETE
H01L 2021/60292		DELETE
H01L 21/603		DELETE
H01L 21/607		DELETE
H01L 21/71		DELETE
H01L 21/74		DELETE
H01L 21/743		DELETE
H01L 21/746		DELETE
H01L 21/76		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 21/7602		DELETE
H01L 21/7605		DELETE
H01L 21/7607		DELETE
H01L 21/761		DELETE
H01L 21/762		DELETE
H01L 21/76202		DELETE
H01L 21/76205		DELETE
H01L 21/76208		DELETE
H01L 21/7621		DELETE
H01L 21/76213		DELETE
H01L 21/76216		DELETE
H01L 21/76218		DELETE
H01L 21/76221		DELETE
H01L 21/76224		DELETE
H01L 21/76227		DELETE
H01L 21/76229		DELETE
H01L 21/76232		DELETE
H01L 21/76235		DELETE
H01L 21/76237		DELETE
H01L 21/76264		DELETE
H01L 21/76267		DELETE
H01L 21/7627		DELETE
H01L 21/76272		DELETE
H01L 21/76275		DELETE
H01L 21/76278		DELETE
H01L 21/76281		DELETE
H01L 21/76283		DELETE
H01L 21/76286		DELETE
H01L 21/76289		DELETE
H01L 21/76291		DELETE
H01L 21/76294		DELETE
H01L 21/76297		DELETE
H01L 21/763		DELETE
H01L 21/764		DELETE
H01L 21/765		DELETE
H01L 21/768		DELETE
H01L 21/76801		DELETE
H01L 21/76802		DELETE
H01L 21/76804		DELETE
H01L 21/76805		DELETE
H01L 21/76807		DELETE
H01L 21/76808		DELETE
H01L 21/7681		DELETE
H01L 21/76811		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 21/76813		DELETE
H01L 21/76814		DELETE
H01L 21/76816		DELETE
H01L 21/76817		DELETE
H01L 21/76819		DELETE
H01L 21/7682		DELETE
H01L 21/76822		DELETE
H01L 21/76823		DELETE
H01L 21/76825		DELETE
H01L 21/76826		DELETE
H01L 21/76828		DELETE
H01L 21/76829		DELETE
H01L 21/76831		DELETE
H01L 21/76832		DELETE
H01L 21/76834		DELETE
H01L 21/76835		DELETE
H01L 21/76837		DELETE
H01L 21/76838		DELETE
H01L 21/7684		DELETE
H01L 21/76841		DELETE
H01L 21/76843		DELETE
H01L 21/76844		DELETE
H01L 21/76846		DELETE
H01L 21/76847		DELETE
H01L 21/76849		DELETE
H01L 21/7685		DELETE
H01L 21/76852		DELETE
H01L 21/76853		DELETE
H01L 21/76855		DELETE
H01L 21/76856		DELETE
H01L 21/76858		DELETE
H01L 21/76859		DELETE
H01L 21/76861		DELETE
H01L 21/76862		DELETE
H01L 21/76864		DELETE
H01L 21/76865		DELETE
H01L 21/76867		DELETE
H01L 21/76868		DELETE
H01L 21/7687		DELETE
H01L 21/76871		DELETE
H01L 21/76873		DELETE
H01L 21/76874		DELETE
H01L 21/76876		DELETE
H01L 21/76877		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 21/76879		DELETE
H01L 21/7688		DELETE
H01L 21/76882		DELETE
H01L 21/76883		DELETE
H01L 21/76885		DELETE
H01L 21/76886		DELETE
H01L 21/76888		DELETE
H01L 21/76889		DELETE
H01L 21/76891		DELETE
H01L 21/76892		DELETE
H01L 21/76894		DELETE
H01L 21/76895		DELETE
H01L 21/76897		DELETE
H01L 21/76898		DELETE
H01L 23/00		DELETE
H01L 23/02		DELETE
H01L 23/04		DELETE
H01L 23/041		DELETE
H01L 23/043		DELETE
H01L 23/045		DELETE
H01L 23/047		DELETE
H01L 23/049		DELETE
H01L 23/051		DELETE
H01L 23/053		DELETE
H01L 23/055		DELETE
H01L 23/057		DELETE
H01L 23/06		DELETE
H01L 23/08		DELETE
H01L 23/10		DELETE
H01L 23/12		DELETE
H01L 23/13		DELETE
H01L 23/14		DELETE
H01L 23/142		DELETE
H01L 23/145		DELETE
H01L 23/147		DELETE
H01L 23/15		DELETE
H01L 23/16		DELETE
H01L 23/18		DELETE
H01L 23/20		DELETE
H01L 23/22		DELETE
H01L 23/24		DELETE
H01L 23/26		DELETE
H01L 23/28		DELETE
H01L 23/29		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 23/291		DELETE
H01L 23/293		DELETE
H01L 23/295		DELETE
H01L 23/296		DELETE
H01L 23/298		DELETE
H01L 23/31		DELETE
H01L 23/3107		DELETE
H01L 23/3114		DELETE
H01L 23/3121		DELETE
H01L 23/3128		DELETE
H01L 23/3135		DELETE
H01L 23/3142		DELETE
H01L 23/315		DELETE
H01L 23/3157		DELETE
H01L 23/3164		DELETE
H01L 23/3171		DELETE
H01L 23/3178		DELETE
H01L 23/3185		DELETE
H01L 23/3192		DELETE
H01L 23/32		DELETE
H01L 23/34		DELETE
H01L 23/345		DELETE
H01L 23/36		DELETE
H01L 23/367		DELETE
H01L 23/3672		DELETE
H01L 23/3675		DELETE
H01L 23/3677		DELETE
H01L 23/373		DELETE
H01L 23/3731		DELETE
H01L 23/3732		DELETE
H01L 23/3733		DELETE
H01L 23/3735		DELETE
H01L 23/3736		DELETE
H01L 23/3737		DELETE
H01L 23/3738		DELETE
H01L 23/38		DELETE
H01L 23/40		DELETE
H01L 23/4006		DELETE
H01L 23/4012		DELETE
H01L 2023/4018		DELETE
H01L 2023/4025		DELETE
H01L 2023/4031		DELETE
H01L 2023/4037		DELETE
H01L 2023/4043		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2023/405		DELETE
H01L 2023/4056		DELETE
H01L 2023/4062		DELETE
H01L 2023/4068		DELETE
H01L 2023/4075		DELETE
H01L 2023/4081		DELETE
H01L 2023/4087		DELETE
H01L 23/4093		DELETE
H01L 23/42		DELETE
H01L 23/427		DELETE
H01L 23/4275		DELETE
H01L 23/433		DELETE
H01L 23/4332		DELETE
H01L 23/4334		DELETE
H01L 23/4336		DELETE
H01L 23/4338		DELETE
H01L 23/44		DELETE
H01L 23/445		DELETE
H01L 23/46		DELETE
H01L 23/467		DELETE
H01L 23/473		DELETE
H01L 23/4735		DELETE
H01L 23/48		DELETE
H01L 23/481		DELETE
H01L 23/482		DELETE
H01L 23/4821		DELETE
H01L 23/4822		DELETE
H01L 23/4824		DELETE
H01L 23/4825		DELETE
H01L 23/4827		DELETE
H01L 23/4828		DELETE
H01L 23/485		DELETE
H01L 23/4855		DELETE
H01L 23/488		DELETE
H01L 23/49		DELETE
H01L 23/492		DELETE
H01L 23/4922		DELETE
H01L 23/4924		DELETE
H01L 23/4926		DELETE
H01L 23/4928		DELETE
H01L 23/495		DELETE
H01L 23/49503		DELETE
H01L 23/49506		DELETE
H01L 23/4951		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 23/49513		DELETE
H01L 23/49517		DELETE
H01L 23/4952		DELETE
H01L 23/49524		DELETE
H01L 23/49527		DELETE
H01L 23/49531		DELETE
H01L 23/49534		DELETE
H01L 23/49537		DELETE
H01L 23/49541		DELETE
H01L 23/49544		DELETE
H01L 23/49548		DELETE
H01L 23/49551		DELETE
H01L 23/49555		DELETE
H01L 23/49558		DELETE
H01L 23/49562		DELETE
H01L 23/49565		DELETE
H01L 23/49568		DELETE
H01L 23/49572		DELETE
H01L 23/49575		DELETE
H01L 23/49579		DELETE
H01L 23/49582		DELETE
H01L 23/49586		DELETE
H01L 23/49589		DELETE
H01L 23/49593		DELETE
H01L 23/49596		DELETE
H01L 23/498		DELETE
H01L 23/49805		DELETE
H01L 23/49811		DELETE
H01L 23/49816		DELETE
H01L 23/49822		DELETE
H01L 23/49827		DELETE
H01L 23/49833		DELETE
H01L 23/49838		DELETE
H01L 23/49844		DELETE
H01L 23/4985		DELETE
H01L 23/49855		DELETE
H01L 23/49861		DELETE
H01L 23/49866		DELETE
H01L 23/49872		DELETE
H01L 23/49877		DELETE
H01L 23/49883		DELETE
H01L 23/49888		DELETE
H01L 23/49894		DELETE
H01L 23/50		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 23/52		DELETE
H01L 23/522		DELETE
H01L 23/5221		DELETE
H01L 23/5222		DELETE
H01L 23/5223		DELETE
H01L 23/5225		DELETE
H01L 23/5226		DELETE
H01L 23/5227		DELETE
H01L 23/5228		DELETE
H01L 23/525		DELETE
H01L 23/5252		DELETE
H01L 23/5254		DELETE
H01L 23/5256		DELETE
H01L 23/5258		DELETE
H01L 23/528		DELETE
H01L 23/5283		DELETE
H01L 23/5286		DELETE
H01L 23/532		DELETE
H01L 23/53204		DELETE
H01L 23/53209		DELETE
H01L 23/53214		DELETE
H01L 23/53219		DELETE
H01L 23/53223		DELETE
H01L 23/53228		DELETE
H01L 23/53233		DELETE
H01L 23/53238		DELETE
H01L 23/53242		DELETE
H01L 23/53247		DELETE
H01L 23/53252		DELETE
H01L 23/53257		DELETE
H01L 23/53261		DELETE
H01L 23/53266		DELETE
H01L 23/53271		DELETE
H01L 23/53276		DELETE
H01L 23/5328		DELETE
H01L 23/53285		DELETE
H01L 23/5329		DELETE
H01L 23/53295		DELETE
H01L 23/535		DELETE
H01L 23/538		DELETE
H01L 23/5381		DELETE
H01L 23/5382		DELETE
H01L 23/5383		DELETE
H01L 23/5384		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 23/5385		DELETE
H01L 23/5386		DELETE
H01L 23/5387		DELETE
H01L 23/5388		DELETE
H01L 23/5389		DELETE
H01L 23/544		DELETE
H01L 23/552		DELETE
H01L 23/556		DELETE
H01L 23/562		DELETE
H01L 23/564		DELETE
H01L 23/57		DELETE
H01L 23/573		DELETE
H01L 23/576		DELETE
H01L 23/58		DELETE
H01L 23/585		DELETE
H01L 23/60		DELETE
H01L 23/62		DELETE
H01L 23/64		DELETE
H01L 23/642		DELETE
H01L 23/645		DELETE
H01L 23/647		DELETE
H01L 23/66		DELETE
H01L 24/00		DELETE
H01L 24/01		DELETE
H01L 24/02		DELETE
H01L 24/03		DELETE
H01L 24/04		DELETE
H01L 24/05		DELETE
H01L 24/06		DELETE
H01L 24/07		DELETE
H01L 24/08		DELETE
H01L 24/09		DELETE
H01L 24/10		DELETE
H01L 24/11		DELETE
H01L 24/12		DELETE
H01L 24/13		DELETE
H01L 24/14		DELETE
H01L 24/15		DELETE
H01L 24/16		DELETE
H01L 24/17		DELETE
H01L 24/18		DELETE
H01L 24/19		DELETE
H01L 24/20		DELETE
H01L 24/23		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 24/24		DELETE
H01L 24/25		DELETE
H01L 24/26		DELETE
H01L 24/27		DELETE
H01L 24/28		DELETE
H01L 24/29		DELETE
H01L 24/30		DELETE
H01L 24/31		DELETE
H01L 24/32		DELETE
H01L 24/33		DELETE
H01L 24/34		DELETE
H01L 24/35		DELETE
H01L 24/36		DELETE
H01L 24/37		DELETE
H01L 24/38		DELETE
H01L 24/39		DELETE
H01L 24/40		DELETE
H01L 24/41		DELETE
H01L 24/42		DELETE
H01L 24/43		DELETE
H01L 24/44		DELETE
H01L 24/45		DELETE
H01L 24/46		DELETE
H01L 24/47		DELETE
H01L 24/48		DELETE
H01L 24/49		DELETE
H01L 24/50		DELETE
H01L 24/63		DELETE
H01L 24/64		DELETE
H01L 24/65		DELETE
H01L 24/66		DELETE
H01L 24/67		DELETE
H01L 24/68		DELETE
H01L 24/69		DELETE
H01L 24/70		DELETE
H01L 24/71		DELETE
H01L 24/72		DELETE
H01L 24/73		DELETE
H01L 24/74		DELETE
H01L 24/741		DELETE
H01L 24/742		DELETE
H01L 24/743		DELETE
H01L 24/744		DELETE
H01L 24/745		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 24/75		DELETE
H01L 24/76		DELETE
H01L 24/77		DELETE
H01L 24/78		DELETE
H01L 24/79		DELETE
H01L 24/799		DELETE
H01L 24/80		DELETE
H01L 24/81		DELETE
H01L 24/82		DELETE
H01L 24/83		DELETE
H01L 24/84		DELETE
H01L 24/85		DELETE
H01L 24/86		DELETE
H01L 24/89		DELETE
H01L 24/90		DELETE
H01L 24/91		DELETE
H01L 24/92		DELETE
H01L 24/93		DELETE
H01L 24/94		DELETE
H01L 24/95		DELETE
H01L 24/96		DELETE
H01L 24/97		DELETE
H01L 24/98		DELETE
H01L 25/00		DELETE
H01L 25/03		DELETE
H01L 25/04		DELETE
H01L 25/041		DELETE
H01L 25/042		DELETE
H01L 25/043		DELETE
H01L 25/065		DELETE
H01L 25/0652		DELETE
H01L 25/0655		DELETE
H01L 25/0657		DELETE
H01L 25/07		DELETE
H01L 25/071		DELETE
H01L 25/072		DELETE
H01L 25/073		DELETE
H01L 25/074		DELETE
H01L 25/075		DELETE
H01L 25/0753		DELETE
H01L 25/0756		DELETE
H01L 25/10		DELETE
H01L 25/105		DELETE
H01L 25/11		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 25/112		DELETE
H01L 25/115		DELETE
H01L 25/117		DELETE
H01L 25/13		DELETE
H01L 25/16		DELETE
H01L 25/162		DELETE
H01L 25/165		DELETE
H01L 25/167		DELETE
H01L 25/18		DELETE
H01L 25/50		DELETE
H01L 2221/10		DELETE
H01L 2221/1005		DELETE
H01L 2221/101		DELETE
H01L 2221/1015		DELETE
H01L 2221/1021		DELETE
H01L 2221/1026		DELETE
H01L 2221/1031		DELETE
H01L 2221/1036		DELETE
H01L 2221/1042		DELETE
H01L 2221/1047		DELETE
H01L 2221/1052		DELETE
H01L 2221/1057		DELETE
H01L 2221/1063		DELETE
H01L 2221/1068		DELETE
H01L 2221/1073		DELETE
H01L 2221/1078		DELETE
H01L 2221/1084		DELETE
H01L 2221/1089		DELETE
H01L 2221/1094		DELETE
H01L 2223/00		DELETE
H01L 2223/544		DELETE
H01L 2223/54406		DELETE
H01L 2223/54413		DELETE
H01L 2223/5442		DELETE
H01L 2223/54426		DELETE
H01L 2223/54433		DELETE
H01L 2223/5444		DELETE
H01L 2223/54446		DELETE
H01L 2223/54453		DELETE
H01L 2223/5446		DELETE
H01L 2223/54466		DELETE
H01L 2223/54473		DELETE
H01L 2223/5448		DELETE
H01L 2223/54486		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2223/54493		DELETE
H01L 2223/58		DELETE
H01L 2223/64		DELETE
H01L 2223/66		DELETE
H01L 2223/6605		DELETE
H01L 2223/6611		DELETE
H01L 2223/6616		DELETE
H01L 2223/6622		DELETE
H01L 2223/6627		DELETE
H01L 2223/6633		DELETE
H01L 2223/6638		DELETE
H01L 2223/6644		DELETE
H01L 2223/665		DELETE
H01L 2223/6655		DELETE
H01L 2223/6661		DELETE
H01L 2223/6666		DELETE
H01L 2223/6672		DELETE
H01L 2223/6677		DELETE
H01L 2223/6683		DELETE
H01L 2223/6688		DELETE
H01L 2223/6694		DELETE
H01L 2224/00		DELETE
H01L 2224/01		DELETE
H01L 2224/02		DELETE
H01L 2224/0212		DELETE
H01L 2224/02122		DELETE
H01L 2224/02123		DELETE
H01L 2224/02125		DELETE
H01L 2224/02126		DELETE
H01L 2224/0213		DELETE
H01L 2224/02135		DELETE
H01L 2224/0214		DELETE
H01L 2224/02141		DELETE
H01L 2224/02145		DELETE
H01L 2224/0215		DELETE
H01L 2224/02163		DELETE
H01L 2224/02165		DELETE
H01L 2224/02166		DELETE
H01L 2224/0217		DELETE
H01L 2224/02175		DELETE
H01L 2224/0218		DELETE
H01L 2224/02181		DELETE
H01L 2224/02185		DELETE
H01L 2224/0219		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/022		DELETE
H01L 2224/02205		DELETE
H01L 2224/02206		DELETE
H01L 2224/0221		DELETE
H01L 2224/02215		DELETE
H01L 2224/02233		DELETE
H01L 2224/02235		DELETE
H01L 2224/0224		DELETE
H01L 2224/02245		DELETE
H01L 2224/0225		DELETE
H01L 2224/02251		DELETE
H01L 2224/02255		DELETE
H01L 2224/0226		DELETE
H01L 2224/023		DELETE
H01L 2224/0231		DELETE
H01L 2224/02311		DELETE
H01L 2224/02313		DELETE
H01L 2224/02315		DELETE
H01L 2224/02317		DELETE
H01L 2224/02319		DELETE
H01L 2224/02321		DELETE
H01L 2224/0233		DELETE
H01L 2224/02331		DELETE
H01L 2224/02333		DELETE
H01L 2224/02335		DELETE
H01L 2224/0235		DELETE
H01L 2224/02351		DELETE
H01L 2224/0236		DELETE
H01L 2224/0237		DELETE
H01L 2224/02371		DELETE
H01L 2224/02372		DELETE
H01L 2224/02373		DELETE
H01L 2224/02375		DELETE
H01L 2224/02377		DELETE
H01L 2224/02379		DELETE
H01L 2224/02381		DELETE
H01L 2224/0239		DELETE
H01L 2224/024		DELETE
H01L 2224/03		DELETE
H01L 2224/03001		DELETE
H01L 2224/03002		DELETE
H01L 2224/03003		DELETE
H01L 2224/03005		DELETE
H01L 2224/03009		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/03011		DELETE
H01L 2224/03013		DELETE
H01L 2224/03015		DELETE
H01L 2224/03019		DELETE
H01L 2224/031		DELETE
H01L 2224/0311		DELETE
H01L 2224/0312		DELETE
H01L 2224/033		DELETE
H01L 2224/0331		DELETE
H01L 2224/03312		DELETE
H01L 2224/03318		DELETE
H01L 2224/0332		DELETE
H01L 2224/0333		DELETE
H01L 2224/03332		DELETE
H01L 2224/03334		DELETE
H01L 2224/034		DELETE
H01L 2224/0341		DELETE
H01L 2224/03416		DELETE
H01L 2224/03418		DELETE
H01L 2224/0342		DELETE
H01L 2224/03422		DELETE
H01L 2224/03424		DELETE
H01L 2224/03426		DELETE
H01L 2224/03428		DELETE
H01L 2224/0343		DELETE
H01L 2224/03436		DELETE
H01L 2224/03438		DELETE
H01L 2224/0344		DELETE
H01L 2224/03442		DELETE
H01L 2224/03444		DELETE
H01L 2224/0345		DELETE
H01L 2224/03452		DELETE
H01L 2224/0346		DELETE
H01L 2224/03462		DELETE
H01L 2224/03464		DELETE
H01L 2224/03466		DELETE
H01L 2224/0347		DELETE
H01L 2224/03472		DELETE
H01L 2224/03474		DELETE
H01L 2224/0348		DELETE
H01L 2224/035		DELETE
H01L 2224/03502		DELETE
H01L 2224/03505		DELETE
H01L 2224/0351		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/03515		DELETE
H01L 2224/0352		DELETE
H01L 2224/03522		DELETE
H01L 2224/03524		DELETE
H01L 2224/0355		DELETE
H01L 2224/03552		DELETE
H01L 2224/03554		DELETE
H01L 2224/036		DELETE
H01L 2224/03602		DELETE
H01L 2224/0361		DELETE
H01L 2224/03612		DELETE
H01L 2224/03614		DELETE
H01L 2224/03616		DELETE
H01L 2224/03618		DELETE
H01L 2224/0362		DELETE
H01L 2224/03622		DELETE
H01L 2224/0363		DELETE
H01L 2224/03632		DELETE
H01L 2224/037		DELETE
H01L 2224/038		DELETE
H01L 2224/0381		DELETE
H01L 2224/0382		DELETE
H01L 2224/03821		DELETE
H01L 2224/03822		DELETE
H01L 2224/03823		DELETE
H01L 2224/03824		DELETE
H01L 2224/03825		DELETE
H01L 2224/03826		DELETE
H01L 2224/03827		DELETE
H01L 2224/03828		DELETE
H01L 2224/03829		DELETE
H01L 2224/0383		DELETE
H01L 2224/03831		DELETE
H01L 2224/0384		DELETE
H01L 2224/03845		DELETE
H01L 2224/03848		DELETE
H01L 2224/03849		DELETE
H01L 2224/039		DELETE
H01L 2224/03901		DELETE
H01L 2224/03902		DELETE
H01L 2224/03903		DELETE
H01L 2224/03906		DELETE
H01L 2224/0391		DELETE
H01L 2224/03912		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/03914		DELETE
H01L 2224/03916		DELETE
H01L 2224/0392		DELETE
H01L 2224/03921		DELETE
H01L 2224/04		DELETE
H01L 2224/0401		DELETE
H01L 2224/04026		DELETE
H01L 2224/04034		DELETE
H01L 2224/04042		DELETE
H01L 2224/0405		DELETE
H01L 2224/04073		DELETE
H01L 2224/04105		DELETE
H01L 2224/05		DELETE
H01L 2224/05001		DELETE
H01L 2224/05005		DELETE
H01L 2224/05006		DELETE
H01L 2224/05007		DELETE
H01L 2224/05008		DELETE
H01L 2224/05009		DELETE
H01L 2224/0501		DELETE
H01L 2224/05011		DELETE
H01L 2224/05012		DELETE
H01L 2224/05013		DELETE
H01L 2224/05014		DELETE
H01L 2224/05015		DELETE
H01L 2224/05016		DELETE
H01L 2224/05017		DELETE
H01L 2224/05018		DELETE
H01L 2224/05019		DELETE
H01L 2224/0502		DELETE
H01L 2224/05022		DELETE
H01L 2224/05023		DELETE
H01L 2224/05024		DELETE
H01L 2224/05025		DELETE
H01L 2224/05026		DELETE
H01L 2224/05027		DELETE
H01L 2224/05073		DELETE
H01L 2224/05075		DELETE
H01L 2224/05076		DELETE
H01L 2224/05078		DELETE
H01L 2224/0508		DELETE
H01L 2224/05082		DELETE
H01L 2224/05083		DELETE
H01L 2224/05084		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/05085		DELETE
H01L 2224/05086		DELETE
H01L 2224/05087		DELETE
H01L 2224/05088		DELETE
H01L 2224/05089		DELETE
H01L 2224/0509		DELETE
H01L 2224/05091		DELETE
H01L 2224/05092		DELETE
H01L 2224/05093		DELETE
H01L 2224/05094		DELETE
H01L 2224/05095		DELETE
H01L 2224/05096		DELETE
H01L 2224/05097		DELETE
H01L 2224/05098		DELETE
H01L 2224/05099		DELETE
H01L 2224/051		DELETE
H01L 2224/05101		DELETE
H01L 2224/05105		DELETE
H01L 2224/05109		DELETE
H01L 2224/05111		DELETE
H01L 2224/05113		DELETE
H01L 2224/05114		DELETE
H01L 2224/05116		DELETE
H01L 2224/05117		DELETE
H01L 2224/05118		DELETE
H01L 2224/0512		DELETE
H01L 2224/05123		DELETE
H01L 2224/05124		DELETE
H01L 2224/05138		DELETE
H01L 2224/05139		DELETE
H01L 2224/05144		DELETE
H01L 2224/05147		DELETE
H01L 2224/05149		DELETE
H01L 2224/05155		DELETE
H01L 2224/05157		DELETE
H01L 2224/0516		DELETE
H01L 2224/05163		DELETE
H01L 2224/05164		DELETE
H01L 2224/05166		DELETE
H01L 2224/05169		DELETE
H01L 2224/0517		DELETE
H01L 2224/05171		DELETE
H01L 2224/05172		DELETE
H01L 2224/05173		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/05176		DELETE
H01L 2224/05178		DELETE
H01L 2224/05179		DELETE
H01L 2224/0518		DELETE
H01L 2224/05181		DELETE
H01L 2224/05183		DELETE
H01L 2224/05184		DELETE
H01L 2224/05186		DELETE
H01L 2224/05187		DELETE
H01L 2224/05188		DELETE
H01L 2224/0519		DELETE
H01L 2224/05191		DELETE
H01L 2224/05193		DELETE
H01L 2224/05194		DELETE
H01L 2224/05195		DELETE
H01L 2224/05198		DELETE
H01L 2224/05199		DELETE
H01L 2224/052		DELETE
H01L 2224/05201		DELETE
H01L 2224/05205		DELETE
H01L 2224/05209		DELETE
H01L 2224/05211		DELETE
H01L 2224/05213		DELETE
H01L 2224/05214		DELETE
H01L 2224/05216		DELETE
H01L 2224/05217		DELETE
H01L 2224/05218		DELETE
H01L 2224/0522		DELETE
H01L 2224/05223		DELETE
H01L 2224/05224		DELETE
H01L 2224/05238		DELETE
H01L 2224/05239		DELETE
H01L 2224/05244		DELETE
H01L 2224/05247		DELETE
H01L 2224/05249		DELETE
H01L 2224/05255		DELETE
H01L 2224/05257		DELETE
H01L 2224/0526		DELETE
H01L 2224/05263		DELETE
H01L 2224/05264		DELETE
H01L 2224/05266		DELETE
H01L 2224/05269		DELETE
H01L 2224/0527		DELETE
H01L 2224/05271		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/05272		DELETE
H01L 2224/05273		DELETE
H01L 2224/05276		DELETE
H01L 2224/05278		DELETE
H01L 2224/05279		DELETE
H01L 2224/0528		DELETE
H01L 2224/05281		DELETE
H01L 2224/05283		DELETE
H01L 2224/05284		DELETE
H01L 2224/05286		DELETE
H01L 2224/05287		DELETE
H01L 2224/05288		DELETE
H01L 2224/0529		DELETE
H01L 2224/05291		DELETE
H01L 2224/05293		DELETE
H01L 2224/05294		DELETE
H01L 2224/05295		DELETE
H01L 2224/05298		DELETE
H01L 2224/05299		DELETE
H01L 2224/053		DELETE
H01L 2224/05301		DELETE
H01L 2224/05305		DELETE
H01L 2224/05309		DELETE
H01L 2224/05311		DELETE
H01L 2224/05313		DELETE
H01L 2224/05314		DELETE
H01L 2224/05316		DELETE
H01L 2224/05317		DELETE
H01L 2224/05318		DELETE
H01L 2224/0532		DELETE
H01L 2224/05323		DELETE
H01L 2224/05324		DELETE
H01L 2224/05338		DELETE
H01L 2224/05339		DELETE
H01L 2224/05344		DELETE
H01L 2224/05347		DELETE
H01L 2224/05349		DELETE
H01L 2224/05355		DELETE
H01L 2224/05357		DELETE
H01L 2224/0536		DELETE
H01L 2224/05363		DELETE
H01L 2224/05364		DELETE
H01L 2224/05366		DELETE
H01L 2224/05369		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/0537		DELETE
H01L 2224/05371		DELETE
H01L 2224/05372		DELETE
H01L 2224/05373		DELETE
H01L 2224/05376		DELETE
H01L 2224/05378		DELETE
H01L 2224/05379		DELETE
H01L 2224/0538		DELETE
H01L 2224/05381		DELETE
H01L 2224/05383		DELETE
H01L 2224/05384		DELETE
H01L 2224/05386		DELETE
H01L 2224/05387		DELETE
H01L 2224/05388		DELETE
H01L 2224/0539		DELETE
H01L 2224/05391		DELETE
H01L 2224/05393		DELETE
H01L 2224/05394		DELETE
H01L 2224/05395		DELETE
H01L 2224/05398		DELETE
H01L 2224/05399		DELETE
H01L 2224/054		DELETE
H01L 2224/05401		DELETE
H01L 2224/05405		DELETE
H01L 2224/05409		DELETE
H01L 2224/05411		DELETE
H01L 2224/05413		DELETE
H01L 2224/05414		DELETE
H01L 2224/05416		DELETE
H01L 2224/05417		DELETE
H01L 2224/05418		DELETE
H01L 2224/0542		DELETE
H01L 2224/05423		DELETE
H01L 2224/05424		DELETE
H01L 2224/05438		DELETE
H01L 2224/05439		DELETE
H01L 2224/05444		DELETE
H01L 2224/05447		DELETE
H01L 2224/05449		DELETE
H01L 2224/05455		DELETE
H01L 2224/05457		DELETE
H01L 2224/0546		DELETE
H01L 2224/05463		DELETE
H01L 2224/05464		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/05466		DELETE
H01L 2224/05469		DELETE
H01L 2224/0547		DELETE
H01L 2224/05471		DELETE
H01L 2224/05472		DELETE
H01L 2224/05473		DELETE
H01L 2224/05476		DELETE
H01L 2224/05478		DELETE
H01L 2224/05479		DELETE
H01L 2224/0548		DELETE
H01L 2224/05481		DELETE
H01L 2224/05483		DELETE
H01L 2224/05484		DELETE
H01L 2224/05486		DELETE
H01L 2224/05487		DELETE
H01L 2224/05488		DELETE
H01L 2224/0549		DELETE
H01L 2224/05491		DELETE
H01L 2224/05493		DELETE
H01L 2224/05494		DELETE
H01L 2224/05495		DELETE
H01L 2224/05498		DELETE
H01L 2224/05499		DELETE
H01L 2224/0554		DELETE
H01L 2224/05541		DELETE
H01L 2224/05546		DELETE
H01L 2224/05547		DELETE
H01L 2224/05548		DELETE
H01L 2224/0555		DELETE
H01L 2224/05551		DELETE
H01L 2224/05552		DELETE
H01L 2224/05553		DELETE
H01L 2224/05554		DELETE
H01L 2224/05555		DELETE
H01L 2224/05556		DELETE
H01L 2224/05557		DELETE
H01L 2224/05558		DELETE
H01L 2224/05559		DELETE
H01L 2224/0556		DELETE
H01L 2224/05561		DELETE
H01L 2224/05562		DELETE
H01L 2224/05563		DELETE
H01L 2224/05564		DELETE
H01L 2224/05565		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/05566		DELETE
H01L 2224/05567		DELETE
H01L 2224/05568		DELETE
H01L 2224/05569		DELETE
H01L 2224/0557		DELETE
H01L 2224/05571		DELETE
H01L 2224/05572		DELETE
H01L 2224/05573		DELETE
H01L 2224/05575		DELETE
H01L 2224/05576		DELETE
H01L 2224/05578		DELETE
H01L 2224/0558		DELETE
H01L 2224/05582		DELETE
H01L 2224/05583		DELETE
H01L 2224/05584		DELETE
H01L 2224/05599		DELETE
H01L 2224/056		DELETE
H01L 2224/05601		DELETE
H01L 2224/05605		DELETE
H01L 2224/05609		DELETE
H01L 2224/05611		DELETE
H01L 2224/05613		DELETE
H01L 2224/05614		DELETE
H01L 2224/05616		DELETE
H01L 2224/05617		DELETE
H01L 2224/05618		DELETE
H01L 2224/0562		DELETE
H01L 2224/05623		DELETE
H01L 2224/05624		DELETE
H01L 2224/05638		DELETE
H01L 2224/05639		DELETE
H01L 2224/05644		DELETE
H01L 2224/05647		DELETE
H01L 2224/05649		DELETE
H01L 2224/05655		DELETE
H01L 2224/05657		DELETE
H01L 2224/0566		DELETE
H01L 2224/05663		DELETE
H01L 2224/05664		DELETE
H01L 2224/05666		DELETE
H01L 2224/05669		DELETE
H01L 2224/0567		DELETE
H01L 2224/05671		DELETE
H01L 2224/05672		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/05673		DELETE
H01L 2224/05676		DELETE
H01L 2224/05678		DELETE
H01L 2224/05679		DELETE
H01L 2224/0568		DELETE
H01L 2224/05681		DELETE
H01L 2224/05683		DELETE
H01L 2224/05684		DELETE
H01L 2224/05686		DELETE
H01L 2224/05687		DELETE
H01L 2224/05688		DELETE
H01L 2224/0569		DELETE
H01L 2224/05691		DELETE
H01L 2224/05693		DELETE
H01L 2224/05694		DELETE
H01L 2224/05695		DELETE
H01L 2224/05698		DELETE
H01L 2224/05699		DELETE
H01L 2224/057		DELETE
H01L 2224/05701		DELETE
H01L 2224/05705		DELETE
H01L 2224/05709		DELETE
H01L 2224/05711		DELETE
H01L 2224/05713		DELETE
H01L 2224/05714		DELETE
H01L 2224/05716		DELETE
H01L 2224/05717		DELETE
H01L 2224/05718		DELETE
H01L 2224/0572		DELETE
H01L 2224/05723		DELETE
H01L 2224/05724		DELETE
H01L 2224/05738		DELETE
H01L 2224/05739		DELETE
H01L 2224/05744		DELETE
H01L 2224/05747		DELETE
H01L 2224/05749		DELETE
H01L 2224/05755		DELETE
H01L 2224/05757		DELETE
H01L 2224/0576		DELETE
H01L 2224/05763		DELETE
H01L 2224/05764		DELETE
H01L 2224/05766		DELETE
H01L 2224/05769		DELETE
H01L 2224/0577		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/05771		DELETE
H01L 2224/05772		DELETE
H01L 2224/05773		DELETE
H01L 2224/05776		DELETE
H01L 2224/05778		DELETE
H01L 2224/05779		DELETE
H01L 2224/0578		DELETE
H01L 2224/05781		DELETE
H01L 2224/05783		DELETE
H01L 2224/05784		DELETE
H01L 2224/05786		DELETE
H01L 2224/05787		DELETE
H01L 2224/05788		DELETE
H01L 2224/0579		DELETE
H01L 2224/05791		DELETE
H01L 2224/05793		DELETE
H01L 2224/05794		DELETE
H01L 2224/05795		DELETE
H01L 2224/05798		DELETE
H01L 2224/05799		DELETE
H01L 2224/058		DELETE
H01L 2224/05801		DELETE
H01L 2224/05805		DELETE
H01L 2224/05809		DELETE
H01L 2224/05811		DELETE
H01L 2224/05813		DELETE
H01L 2224/05814		DELETE
H01L 2224/05816		DELETE
H01L 2224/05817		DELETE
H01L 2224/05818		DELETE
H01L 2224/0582		DELETE
H01L 2224/05823		DELETE
H01L 2224/05824		DELETE
H01L 2224/05838		DELETE
H01L 2224/05839		DELETE
H01L 2224/05844		DELETE
H01L 2224/05847		DELETE
H01L 2224/05849		DELETE
H01L 2224/05855		DELETE
H01L 2224/05857		DELETE
H01L 2224/0586		DELETE
H01L 2224/05863		DELETE
H01L 2224/05864		DELETE
H01L 2224/05866		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/05869		DELETE
H01L 2224/0587		DELETE
H01L 2224/05871		DELETE
H01L 2224/05872		DELETE
H01L 2224/05873		DELETE
H01L 2224/05876		DELETE
H01L 2224/05878		DELETE
H01L 2224/05879		DELETE
H01L 2224/0588		DELETE
H01L 2224/05881		DELETE
H01L 2224/05883		DELETE
H01L 2224/05884		DELETE
H01L 2224/05886		DELETE
H01L 2224/05887		DELETE
H01L 2224/05888		DELETE
H01L 2224/0589		DELETE
H01L 2224/05891		DELETE
H01L 2224/05893		DELETE
H01L 2224/05894		DELETE
H01L 2224/05895		DELETE
H01L 2224/05898		DELETE
H01L 2224/05899		DELETE
H01L 2224/059		DELETE
H01L 2224/05901		DELETE
H01L 2224/05905		DELETE
H01L 2224/05909		DELETE
H01L 2224/05911		DELETE
H01L 2224/05913		DELETE
H01L 2224/05914		DELETE
H01L 2224/05916		DELETE
H01L 2224/05917		DELETE
H01L 2224/05918		DELETE
H01L 2224/0592		DELETE
H01L 2224/05923		DELETE
H01L 2224/05924		DELETE
H01L 2224/05938		DELETE
H01L 2224/05939		DELETE
H01L 2224/05944		DELETE
H01L 2224/05947		DELETE
H01L 2224/05949		DELETE
H01L 2224/05955		DELETE
H01L 2224/05957		DELETE
H01L 2224/0596		DELETE
H01L 2224/05963		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/05964		DELETE
H01L 2224/05966		DELETE
H01L 2224/05969		DELETE
H01L 2224/0597		DELETE
H01L 2224/05971		DELETE
H01L 2224/05972		DELETE
H01L 2224/05973		DELETE
H01L 2224/05976		DELETE
H01L 2224/05978		DELETE
H01L 2224/05979		DELETE
H01L 2224/0598		DELETE
H01L 2224/05981		DELETE
H01L 2224/05983		DELETE
H01L 2224/05984		DELETE
H01L 2224/05986		DELETE
H01L 2224/05987		DELETE
H01L 2224/05988		DELETE
H01L 2224/0599		DELETE
H01L 2224/05991		DELETE
H01L 2224/05993		DELETE
H01L 2224/05994		DELETE
H01L 2224/05995		DELETE
H01L 2224/05998		DELETE
H01L 2224/05999		DELETE
H01L 2224/06		DELETE
H01L 2224/0601		DELETE
H01L 2224/0603		DELETE
H01L 2224/0605		DELETE
H01L 2224/06051		DELETE
H01L 2224/061		DELETE
H01L 2224/06102		DELETE
H01L 2224/0612		DELETE
H01L 2224/0613		DELETE
H01L 2224/06131		DELETE
H01L 2224/06132		DELETE
H01L 2224/06133		DELETE
H01L 2224/06134		DELETE
H01L 2224/06135		DELETE
H01L 2224/06136		DELETE
H01L 2224/06137		DELETE
H01L 2224/06138		DELETE
H01L 2224/06139		DELETE
H01L 2224/0614		DELETE
H01L 2224/06141		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/06142		DELETE
H01L 2224/06143		DELETE
H01L 2224/06144		DELETE
H01L 2224/06145		DELETE
H01L 2224/06146		DELETE
H01L 2224/06147		DELETE
H01L 2224/06148		DELETE
H01L 2224/06149		DELETE
H01L 2224/0615		DELETE
H01L 2224/06151		DELETE
H01L 2224/06152		DELETE
H01L 2224/06153		DELETE
H01L 2224/06154		DELETE
H01L 2224/06155		DELETE
H01L 2224/06156		DELETE
H01L 2224/06157		DELETE
H01L 2224/06158		DELETE
H01L 2224/06159		DELETE
H01L 2224/0616		DELETE
H01L 2224/06163		DELETE
H01L 2224/06164		DELETE
H01L 2224/06165		DELETE
H01L 2224/06166		DELETE
H01L 2224/06167		DELETE
H01L 2224/06168		DELETE
H01L 2224/06169		DELETE
H01L 2224/06177		DELETE
H01L 2224/06179		DELETE
H01L 2224/0618		DELETE
H01L 2224/06181		DELETE
H01L 2224/06182		DELETE
H01L 2224/06183		DELETE
H01L 2224/06187		DELETE
H01L 2224/06188		DELETE
H01L 2224/06189		DELETE
H01L 2224/065		DELETE
H01L 2224/06505		DELETE
H01L 2224/0651		DELETE
H01L 2224/06515		DELETE
H01L 2224/06517		DELETE
H01L 2224/06519		DELETE
H01L 2224/07		DELETE
H01L 2224/08		DELETE
H01L 2224/0801		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/0805		DELETE
H01L 2224/08052		DELETE
H01L 2224/08053		DELETE
H01L 2224/08054		DELETE
H01L 2224/08055		DELETE
H01L 2224/08056		DELETE
H01L 2224/08057		DELETE
H01L 2224/08058		DELETE
H01L 2224/08059		DELETE
H01L 2224/0807		DELETE
H01L 2224/081		DELETE
H01L 2224/08111		DELETE
H01L 2224/08112		DELETE
H01L 2224/08113		DELETE
H01L 2224/0812		DELETE
H01L 2224/08121		DELETE
H01L 2224/08123		DELETE
H01L 2224/08135		DELETE
H01L 2224/08137		DELETE
H01L 2224/08145		DELETE
H01L 2224/08146		DELETE
H01L 2224/08147		DELETE
H01L 2224/08148		DELETE
H01L 2224/08151		DELETE
H01L 2224/08153		DELETE
H01L 2224/08155		DELETE
H01L 2224/0816		DELETE
H01L 2224/08163		DELETE
H01L 2224/08165		DELETE
H01L 2224/08167		DELETE
H01L 2224/08168		DELETE
H01L 2224/08175		DELETE
H01L 2224/08183		DELETE
H01L 2224/08187		DELETE
H01L 2224/08188		DELETE
H01L 2224/08195		DELETE
H01L 2224/08197		DELETE
H01L 2224/08198		DELETE
H01L 2224/08221		DELETE
H01L 2224/08225		DELETE
H01L 2224/0823		DELETE
H01L 2224/08233		DELETE
H01L 2224/08235		DELETE
H01L 2224/08237		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/08238		DELETE
H01L 2224/08245		DELETE
H01L 2224/08253		DELETE
H01L 2224/08257		DELETE
H01L 2224/08258		DELETE
H01L 2224/08265		DELETE
H01L 2224/08267		DELETE
H01L 2224/08268		DELETE
H01L 2224/085		DELETE
H01L 2224/08501		DELETE
H01L 2224/08502		DELETE
H01L 2224/08503		DELETE
H01L 2224/08505		DELETE
H01L 2224/08506		DELETE
H01L 2224/09		DELETE
H01L 2224/0901		DELETE
H01L 2224/0903		DELETE
H01L 2224/0905		DELETE
H01L 2224/09051		DELETE
H01L 2224/09055		DELETE
H01L 2224/091		DELETE
H01L 2224/09102		DELETE
H01L 2224/09103		DELETE
H01L 2224/09104		DELETE
H01L 2224/0912		DELETE
H01L 2224/0913		DELETE
H01L 2224/09132		DELETE
H01L 2224/09133		DELETE
H01L 2224/09134		DELETE
H01L 2224/09135		DELETE
H01L 2224/0914		DELETE
H01L 2224/09142		DELETE
H01L 2224/09143		DELETE
H01L 2224/09144		DELETE
H01L 2224/09145		DELETE
H01L 2224/0915		DELETE
H01L 2224/09151		DELETE
H01L 2224/09152		DELETE
H01L 2224/09153		DELETE
H01L 2224/09154		DELETE
H01L 2224/09155		DELETE
H01L 2224/09156		DELETE
H01L 2224/0916		DELETE
H01L 2224/09163		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/09164		DELETE
H01L 2224/09165		DELETE
H01L 2224/09177		DELETE
H01L 2224/09179		DELETE
H01L 2224/0918		DELETE
H01L 2224/09181		DELETE
H01L 2224/09183		DELETE
H01L 2224/095		DELETE
H01L 2224/09505		DELETE
H01L 2224/0951		DELETE
H01L 2224/09515		DELETE
H01L 2224/09517		DELETE
H01L 2224/09519		DELETE
H01L 2224/10		DELETE
H01L 2224/1012		DELETE
H01L 2224/10122		DELETE
H01L 2224/10125		DELETE
H01L 2224/10126		DELETE
H01L 2224/10135		DELETE
H01L 2224/10145		DELETE
H01L 2224/10152		DELETE
H01L 2224/10155		DELETE
H01L 2224/10156		DELETE
H01L 2224/10165		DELETE
H01L 2224/10175		DELETE
H01L 2224/11		DELETE
H01L 2224/11001		DELETE
H01L 2224/11002		DELETE
H01L 2224/11003		DELETE
H01L 2224/11005		DELETE
H01L 2224/11009		DELETE
H01L 2224/11011		DELETE
H01L 2224/11013		DELETE
H01L 2224/11015		DELETE
H01L 2224/11019		DELETE
H01L 2224/111		DELETE
H01L 2224/1111		DELETE
H01L 2224/1112		DELETE
H01L 2224/113		DELETE
H01L 2224/1131		DELETE
H01L 2224/11312		DELETE
H01L 2224/11318		DELETE
H01L 2224/1132		DELETE
H01L 2224/1133		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/11332		DELETE
H01L 2224/11334		DELETE
H01L 2224/1134		DELETE
H01L 2224/114		DELETE
H01L 2224/1141		DELETE
H01L 2224/11416		DELETE
H01L 2224/11418		DELETE
H01L 2224/1142		DELETE
H01L 2224/11422		DELETE
H01L 2224/11424		DELETE
H01L 2224/11426		DELETE
H01L 2224/11428		DELETE
H01L 2224/1143		DELETE
H01L 2224/11436		DELETE
H01L 2224/11438		DELETE
H01L 2224/1144		DELETE
H01L 2224/11442		DELETE
H01L 2224/11444		DELETE
H01L 2224/1145		DELETE
H01L 2224/11452		DELETE
H01L 2224/1146		DELETE
H01L 2224/11462		DELETE
H01L 2224/11464		DELETE
H01L 2224/11466		DELETE
H01L 2224/1147		DELETE
H01L 2224/11472		DELETE
H01L 2224/11474		DELETE
H01L 2224/1148		DELETE
H01L 2224/115		DELETE
H01L 2224/11502		DELETE
H01L 2224/11505		DELETE
H01L 2224/1151		DELETE
H01L 2224/11515		DELETE
H01L 2224/1152		DELETE
H01L 2224/11522		DELETE
H01L 2224/11524		DELETE
H01L 2224/11526		DELETE
H01L 2224/1155		DELETE
H01L 2224/11552		DELETE
H01L 2224/11554		DELETE
H01L 2224/116		DELETE
H01L 2224/11602		DELETE
H01L 2224/1161		DELETE
H01L 2224/11612		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/11614		DELETE
H01L 2224/11616		DELETE
H01L 2224/11618		DELETE
H01L 2224/1162		DELETE
H01L 2224/11622		DELETE
H01L 2224/1163		DELETE
H01L 2224/11632		DELETE
H01L 2224/117		DELETE
H01L 2224/118		DELETE
H01L 2224/1181		DELETE
H01L 2224/1182		DELETE
H01L 2224/11821		DELETE
H01L 2224/11822		DELETE
H01L 2224/11823		DELETE
H01L 2224/11824		DELETE
H01L 2224/11825		DELETE
H01L 2224/11826		DELETE
H01L 2224/11827		DELETE
H01L 2224/1183		DELETE
H01L 2224/11831		DELETE
H01L 2224/1184		DELETE
H01L 2224/11845		DELETE
H01L 2224/11848		DELETE
H01L 2224/11849		DELETE
H01L 2224/119		DELETE
H01L 2224/11901		DELETE
H01L 2224/11902		DELETE
H01L 2224/11903		DELETE
H01L 2224/11906		DELETE
H01L 2224/1191		DELETE
H01L 2224/11912		DELETE
H01L 2224/11914		DELETE
H01L 2224/11916		DELETE
H01L 2224/12		DELETE
H01L 2224/12105		DELETE
H01L 2224/13		DELETE
H01L 2224/13001		DELETE
H01L 2224/13005		DELETE
H01L 2224/13006		DELETE
H01L 2224/13007		DELETE
H01L 2224/13008		DELETE
H01L 2224/13009		DELETE
H01L 2224/1301		DELETE
H01L 2224/13011		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/13012		DELETE
H01L 2224/13013		DELETE
H01L 2224/13014		DELETE
H01L 2224/13015		DELETE
H01L 2224/13016		DELETE
H01L 2224/13017		DELETE
H01L 2224/13018		DELETE
H01L 2224/13019		DELETE
H01L 2224/1302		DELETE
H01L 2224/13021		DELETE
H01L 2224/13022		DELETE
H01L 2224/13023		DELETE
H01L 2224/13024		DELETE
H01L 2224/13025		DELETE
H01L 2224/13026		DELETE
H01L 2224/13027		DELETE
H01L 2224/13028		DELETE
H01L 2224/13075		DELETE
H01L 2224/13076		DELETE
H01L 2224/13078		DELETE
H01L 2224/1308		DELETE
H01L 2224/13082		DELETE
H01L 2224/13083		DELETE
H01L 2224/13084		DELETE
H01L 2224/13099		DELETE
H01L 2224/131		DELETE
H01L 2224/13101		DELETE
H01L 2224/13105		DELETE
H01L 2224/13109		DELETE
H01L 2224/13111		DELETE
H01L 2224/13113		DELETE
H01L 2224/13114		DELETE
H01L 2224/13116		DELETE
H01L 2224/13117		DELETE
H01L 2224/13118		DELETE
H01L 2224/1312		DELETE
H01L 2224/13123		DELETE
H01L 2224/13124		DELETE
H01L 2224/13138		DELETE
H01L 2224/13139		DELETE
H01L 2224/13144		DELETE
H01L 2224/13147		DELETE
H01L 2224/13149		DELETE
H01L 2224/13155		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/13157		DELETE
H01L 2224/1316		DELETE
H01L 2224/13163		DELETE
H01L 2224/13164		DELETE
H01L 2224/13166		DELETE
H01L 2224/13169		DELETE
H01L 2224/1317		DELETE
H01L 2224/13171		DELETE
H01L 2224/13172		DELETE
H01L 2224/13173		DELETE
H01L 2224/13176		DELETE
H01L 2224/13178		DELETE
H01L 2224/13179		DELETE
H01L 2224/1318		DELETE
H01L 2224/13181		DELETE
H01L 2224/13183		DELETE
H01L 2224/13184		DELETE
H01L 2224/13186		DELETE
H01L 2224/13187		DELETE
H01L 2224/13188		DELETE
H01L 2224/1319		DELETE
H01L 2224/13191		DELETE
H01L 2224/13193		DELETE
H01L 2224/13194		DELETE
H01L 2224/13195		DELETE
H01L 2224/13198		DELETE
H01L 2224/13199		DELETE
H01L 2224/132		DELETE
H01L 2224/13201		DELETE
H01L 2224/13205		DELETE
H01L 2224/13209		DELETE
H01L 2224/13211		DELETE
H01L 2224/13213		DELETE
H01L 2224/13214		DELETE
H01L 2224/13216		DELETE
H01L 2224/13217		DELETE
H01L 2224/13218		DELETE
H01L 2224/1322		DELETE
H01L 2224/13223		DELETE
H01L 2224/13224		DELETE
H01L 2224/13238		DELETE
H01L 2224/13239		DELETE
H01L 2224/13244		DELETE
H01L 2224/13247		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/13249		DELETE
H01L 2224/13255		DELETE
H01L 2224/13257		DELETE
H01L 2224/1326		DELETE
H01L 2224/13263		DELETE
H01L 2224/13264		DELETE
H01L 2224/13266		DELETE
H01L 2224/13269		DELETE
H01L 2224/1327		DELETE
H01L 2224/13271		DELETE
H01L 2224/13272		DELETE
H01L 2224/13273		DELETE
H01L 2224/13276		DELETE
H01L 2224/13278		DELETE
H01L 2224/13279		DELETE
H01L 2224/1328		DELETE
H01L 2224/13281		DELETE
H01L 2224/13283		DELETE
H01L 2224/13284		DELETE
H01L 2224/13286		DELETE
H01L 2224/13287		DELETE
H01L 2224/13288		DELETE
H01L 2224/1329		DELETE
H01L 2224/13291		DELETE
H01L 2224/13293		DELETE
H01L 2224/13294		DELETE
H01L 2224/13295		DELETE
H01L 2224/13298		DELETE
H01L 2224/13299		DELETE
H01L 2224/133		DELETE
H01L 2224/13301		DELETE
H01L 2224/13305		DELETE
H01L 2224/13309		DELETE
H01L 2224/13311		DELETE
H01L 2224/13313		DELETE
H01L 2224/13314		DELETE
H01L 2224/13316		DELETE
H01L 2224/13317		DELETE
H01L 2224/13318		DELETE
H01L 2224/1332		DELETE
H01L 2224/13323		DELETE
H01L 2224/13324		DELETE
H01L 2224/13338		DELETE
H01L 2224/13339		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/13344		DELETE
H01L 2224/13347		DELETE
H01L 2224/13349		DELETE
H01L 2224/13355		DELETE
H01L 2224/13357		DELETE
H01L 2224/1336		DELETE
H01L 2224/13363		DELETE
H01L 2224/13364		DELETE
H01L 2224/13366		DELETE
H01L 2224/13369		DELETE
H01L 2224/1337		DELETE
H01L 2224/13371		DELETE
H01L 2224/13372		DELETE
H01L 2224/13373		DELETE
H01L 2224/13376		DELETE
H01L 2224/13378		DELETE
H01L 2224/13379		DELETE
H01L 2224/1338		DELETE
H01L 2224/13381		DELETE
H01L 2224/13383		DELETE
H01L 2224/13384		DELETE
H01L 2224/13386		DELETE
H01L 2224/13387		DELETE
H01L 2224/13388		DELETE
H01L 2224/1339		DELETE
H01L 2224/13391		DELETE
H01L 2224/13393		DELETE
H01L 2224/13394		DELETE
H01L 2224/13395		DELETE
H01L 2224/13398		DELETE
H01L 2224/13399		DELETE
H01L 2224/134		DELETE
H01L 2224/13401		DELETE
H01L 2224/13405		DELETE
H01L 2224/13409		DELETE
H01L 2224/13411		DELETE
H01L 2224/13413		DELETE
H01L 2224/13414		DELETE
H01L 2224/13416		DELETE
H01L 2224/13417		DELETE
H01L 2224/13418		DELETE
H01L 2224/1342		DELETE
H01L 2224/13423		DELETE
H01L 2224/13424		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/13438		DELETE
H01L 2224/13439		DELETE
H01L 2224/13444		DELETE
H01L 2224/13447		DELETE
H01L 2224/13449		DELETE
H01L 2224/13455		DELETE
H01L 2224/13457		DELETE
H01L 2224/1346		DELETE
H01L 2224/13463		DELETE
H01L 2224/13464		DELETE
H01L 2224/13466		DELETE
H01L 2224/13469		DELETE
H01L 2224/1347		DELETE
H01L 2224/13471		DELETE
H01L 2224/13472		DELETE
H01L 2224/13473		DELETE
H01L 2224/13476		DELETE
H01L 2224/13478		DELETE
H01L 2224/13479		DELETE
H01L 2224/1348		DELETE
H01L 2224/13481		DELETE
H01L 2224/13483		DELETE
H01L 2224/13484		DELETE
H01L 2224/13486		DELETE
H01L 2224/13487		DELETE
H01L 2224/13488		DELETE
H01L 2224/1349		DELETE
H01L 2224/13491		DELETE
H01L 2224/13493		DELETE
H01L 2224/13494		DELETE
H01L 2224/13495		DELETE
H01L 2224/13498		DELETE
H01L 2224/13499		DELETE
H01L 2224/1354		DELETE
H01L 2224/13541		DELETE
H01L 2224/1355		DELETE
H01L 2224/13551		DELETE
H01L 2224/13552		DELETE
H01L 2224/13553		DELETE
H01L 2224/1356		DELETE
H01L 2224/13561		DELETE
H01L 2224/13562		DELETE
H01L 2224/13563		DELETE
H01L 2224/13564		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/13565		DELETE
H01L 2224/13566		DELETE
H01L 2224/1357		DELETE
H01L 2224/13575		DELETE
H01L 2224/13576		DELETE
H01L 2224/13578		DELETE
H01L 2224/1358		DELETE
H01L 2224/13582		DELETE
H01L 2224/13583		DELETE
H01L 2224/13584		DELETE
H01L 2224/13599		DELETE
H01L 2224/136		DELETE
H01L 2224/13601		DELETE
H01L 2224/13605		DELETE
H01L 2224/13609		DELETE
H01L 2224/13611		DELETE
H01L 2224/13613		DELETE
H01L 2224/13614		DELETE
H01L 2224/13616		DELETE
H01L 2224/13617		DELETE
H01L 2224/13618		DELETE
H01L 2224/1362		DELETE
H01L 2224/13623		DELETE
H01L 2224/13624		DELETE
H01L 2224/13638		DELETE
H01L 2224/13639		DELETE
H01L 2224/13644		DELETE
H01L 2224/13647		DELETE
H01L 2224/13649		DELETE
H01L 2224/13655		DELETE
H01L 2224/13657		DELETE
H01L 2224/1366		DELETE
H01L 2224/13663		DELETE
H01L 2224/13664		DELETE
H01L 2224/13666		DELETE
H01L 2224/13669		DELETE
H01L 2224/1367		DELETE
H01L 2224/13671		DELETE
H01L 2224/13672		DELETE
H01L 2224/13673		DELETE
H01L 2224/13676		DELETE
H01L 2224/13678		DELETE
H01L 2224/13679		DELETE
H01L 2224/1368		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/13681		DELETE
H01L 2224/13683		DELETE
H01L 2224/13684		DELETE
H01L 2224/13686		DELETE
H01L 2224/13687		DELETE
H01L 2224/13688		DELETE
H01L 2224/1369		DELETE
H01L 2224/13691		DELETE
H01L 2224/13693		DELETE
H01L 2224/13694		DELETE
H01L 2224/13695		DELETE
H01L 2224/13698		DELETE
H01L 2224/13699		DELETE
H01L 2224/137		DELETE
H01L 2224/13701		DELETE
H01L 2224/13705		DELETE
H01L 2224/13709		DELETE
H01L 2224/13711		DELETE
H01L 2224/13713		DELETE
H01L 2224/13714		DELETE
H01L 2224/13716		DELETE
H01L 2224/13717		DELETE
H01L 2224/13718		DELETE
H01L 2224/1372		DELETE
H01L 2224/13723		DELETE
H01L 2224/13724		DELETE
H01L 2224/13738		DELETE
H01L 2224/13739		DELETE
H01L 2224/13744		DELETE
H01L 2224/13747		DELETE
H01L 2224/13749		DELETE
H01L 2224/13755		DELETE
H01L 2224/13757		DELETE
H01L 2224/1376		DELETE
H01L 2224/13763		DELETE
H01L 2224/13764		DELETE
H01L 2224/13766		DELETE
H01L 2224/13769		DELETE
H01L 2224/1377		DELETE
H01L 2224/13771		DELETE
H01L 2224/13772		DELETE
H01L 2224/13773		DELETE
H01L 2224/13776		DELETE
H01L 2224/13778		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/13779		DELETE
H01L 2224/1378		DELETE
H01L 2224/13781		DELETE
H01L 2224/13783		DELETE
H01L 2224/13784		DELETE
H01L 2224/13786		DELETE
H01L 2224/13787		DELETE
H01L 2224/13788		DELETE
H01L 2224/1379		DELETE
H01L 2224/13791		DELETE
H01L 2224/13793		DELETE
H01L 2224/13794		DELETE
H01L 2224/13795		DELETE
H01L 2224/13798		DELETE
H01L 2224/13799		DELETE
H01L 2224/138		DELETE
H01L 2224/13801		DELETE
H01L 2224/13805		DELETE
H01L 2224/13809		DELETE
H01L 2224/13811		DELETE
H01L 2224/13813		DELETE
H01L 2224/13814		DELETE
H01L 2224/13816		DELETE
H01L 2224/13817		DELETE
H01L 2224/13818		DELETE
H01L 2224/1382		DELETE
H01L 2224/13823		DELETE
H01L 2224/13824		DELETE
H01L 2224/13838		DELETE
H01L 2224/13839		DELETE
H01L 2224/13844		DELETE
H01L 2224/13847		DELETE
H01L 2224/13849		DELETE
H01L 2224/13855		DELETE
H01L 2224/13857		DELETE
H01L 2224/1386		DELETE
H01L 2224/13863		DELETE
H01L 2224/13864		DELETE
H01L 2224/13866		DELETE
H01L 2224/13869		DELETE
H01L 2224/1387		DELETE
H01L 2224/13871		DELETE
H01L 2224/13872		DELETE
H01L 2224/13873		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/13876		DELETE
H01L 2224/13878		DELETE
H01L 2224/13879		DELETE
H01L 2224/1388		DELETE
H01L 2224/13881		DELETE
H01L 2224/13883		DELETE
H01L 2224/13884		DELETE
H01L 2224/13886		DELETE
H01L 2224/13887		DELETE
H01L 2224/13888		DELETE
H01L 2224/1389		DELETE
H01L 2224/13891		DELETE
H01L 2224/13893		DELETE
H01L 2224/13894		DELETE
H01L 2224/13895		DELETE
H01L 2224/13898		DELETE
H01L 2224/13899		DELETE
H01L 2224/139		DELETE
H01L 2224/13901		DELETE
H01L 2224/13905		DELETE
H01L 2224/13909		DELETE
H01L 2224/13911		DELETE
H01L 2224/13913		DELETE
H01L 2224/13914		DELETE
H01L 2224/13916		DELETE
H01L 2224/13917		DELETE
H01L 2224/13918		DELETE
H01L 2224/1392		DELETE
H01L 2224/13923		DELETE
H01L 2224/13924		DELETE
H01L 2224/13938		DELETE
H01L 2224/13939		DELETE
H01L 2224/13944		DELETE
H01L 2224/13947		DELETE
H01L 2224/13949		DELETE
H01L 2224/13955		DELETE
H01L 2224/13957		DELETE
H01L 2224/1396		DELETE
H01L 2224/13963		DELETE
H01L 2224/13964		DELETE
H01L 2224/13966		DELETE
H01L 2224/13969		DELETE
H01L 2224/1397		DELETE
H01L 2224/13971		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/13972		DELETE
H01L 2224/13973		DELETE
H01L 2224/13976		DELETE
H01L 2224/13978		DELETE
H01L 2224/13979		DELETE
H01L 2224/1398		DELETE
H01L 2224/13981		DELETE
H01L 2224/13983		DELETE
H01L 2224/13984		DELETE
H01L 2224/13986		DELETE
H01L 2224/13987		DELETE
H01L 2224/13988		DELETE
H01L 2224/1399		DELETE
H01L 2224/13991		DELETE
H01L 2224/13993		DELETE
H01L 2224/13994		DELETE
H01L 2224/13995		DELETE
H01L 2224/13998		DELETE
H01L 2224/13999		DELETE
H01L 2224/14		DELETE
H01L 2224/1401		DELETE
H01L 2224/1403		DELETE
H01L 2224/1405		DELETE
H01L 2224/14051		DELETE
H01L 2224/141		DELETE
H01L 2224/14104		DELETE
H01L 2224/1411		DELETE
H01L 2224/1412		DELETE
H01L 2224/1413		DELETE
H01L 2224/14131		DELETE
H01L 2224/14132		DELETE
H01L 2224/14133		DELETE
H01L 2224/14134		DELETE
H01L 2224/14135		DELETE
H01L 2224/14136		DELETE
H01L 2224/1414		DELETE
H01L 2224/14141		DELETE
H01L 2224/14142		DELETE
H01L 2224/14143		DELETE
H01L 2224/14144		DELETE
H01L 2224/14145		DELETE
H01L 2224/14146		DELETE
H01L 2224/1415		DELETE
H01L 2224/14151		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/14152		DELETE
H01L 2224/14153		DELETE
H01L 2224/14154		DELETE
H01L 2224/14155		DELETE
H01L 2224/14156		DELETE
H01L 2224/1416		DELETE
H01L 2224/14163		DELETE
H01L 2224/14164		DELETE
H01L 2224/14165		DELETE
H01L 2224/14166		DELETE
H01L 2224/14177		DELETE
H01L 2224/14179		DELETE
H01L 2224/1418		DELETE
H01L 2224/14181		DELETE
H01L 2224/14183		DELETE
H01L 2224/145		DELETE
H01L 2224/14505		DELETE
H01L 2224/1451		DELETE
H01L 2224/14515		DELETE
H01L 2224/14517		DELETE
H01L 2224/14519		DELETE
H01L 2224/15		DELETE
H01L 2224/16		DELETE
H01L 2224/1601		DELETE
H01L 2224/16012		DELETE
H01L 2224/16013		DELETE
H01L 2224/16014		DELETE
H01L 2224/1605		DELETE
H01L 2224/16052		DELETE
H01L 2224/16054		DELETE
H01L 2224/16055		DELETE
H01L 2224/16056		DELETE
H01L 2224/16057		DELETE
H01L 2224/16058		DELETE
H01L 2224/16059		DELETE
H01L 2224/1607		DELETE
H01L 2224/161		DELETE
H01L 2224/16104		DELETE
H01L 2224/16105		DELETE
H01L 2224/16106		DELETE
H01L 2224/16108		DELETE
H01L 2224/16111		DELETE
H01L 2224/16112		DELETE
H01L 2224/16113		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/1613		DELETE
H01L 2224/16135		DELETE
H01L 2224/16137		DELETE
H01L 2224/16141		DELETE
H01L 2224/16145		DELETE
H01L 2224/16146		DELETE
H01L 2224/16147		DELETE
H01L 2224/16148		DELETE
H01L 2224/16151		DELETE
H01L 2224/16153		DELETE
H01L 2224/16155		DELETE
H01L 2224/16157		DELETE
H01L 2224/1616		DELETE
H01L 2224/16163		DELETE
H01L 2224/16165		DELETE
H01L 2224/16167		DELETE
H01L 2224/16168		DELETE
H01L 2224/16175		DELETE
H01L 2224/16183		DELETE
H01L 2224/16187		DELETE
H01L 2224/16188		DELETE
H01L 2224/16195		DELETE
H01L 2224/16197		DELETE
H01L 2224/16198		DELETE
H01L 2224/16221		DELETE
H01L 2224/16225		DELETE
H01L 2224/16227		DELETE
H01L 2224/1623		DELETE
H01L 2224/16233		DELETE
H01L 2224/16235		DELETE
H01L 2224/16237		DELETE
H01L 2224/16238		DELETE
H01L 2224/1624		DELETE
H01L 2224/16245		DELETE
H01L 2224/16253		DELETE
H01L 2224/16257		DELETE
H01L 2224/16258		DELETE
H01L 2224/1626		DELETE
H01L 2224/16265		DELETE
H01L 2224/16267		DELETE
H01L 2224/16268		DELETE
H01L 2224/165		DELETE
H01L 2224/16501		DELETE
H01L 2224/16502		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/16503		DELETE
H01L 2224/16505		DELETE
H01L 2224/16506		DELETE
H01L 2224/16507		DELETE
H01L 2224/17		DELETE
H01L 2224/1701		DELETE
H01L 2224/1703		DELETE
H01L 2224/1705		DELETE
H01L 2224/17051		DELETE
H01L 2224/17055		DELETE
H01L 2224/171		DELETE
H01L 2224/17104		DELETE
H01L 2224/17106		DELETE
H01L 2224/17107		DELETE
H01L 2224/1712		DELETE
H01L 2224/1713		DELETE
H01L 2224/17132		DELETE
H01L 2224/17133		DELETE
H01L 2224/17134		DELETE
H01L 2224/17135		DELETE
H01L 2224/17136		DELETE
H01L 2224/1714		DELETE
H01L 2224/17142		DELETE
H01L 2224/17143		DELETE
H01L 2224/17144		DELETE
H01L 2224/17145		DELETE
H01L 2224/17146		DELETE
H01L 2224/1715		DELETE
H01L 2224/17151		DELETE
H01L 2224/17152		DELETE
H01L 2224/17153		DELETE
H01L 2224/17154		DELETE
H01L 2224/17155		DELETE
H01L 2224/17156		DELETE
H01L 2224/1716		DELETE
H01L 2224/17163		DELETE
H01L 2224/17164		DELETE
H01L 2224/17165		DELETE
H01L 2224/17166		DELETE
H01L 2224/17177		DELETE
H01L 2224/17179		DELETE
H01L 2224/1718		DELETE
H01L 2224/17181		DELETE
H01L 2224/17183		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/175		DELETE
H01L 2224/17505		DELETE
H01L 2224/1751		DELETE
H01L 2224/17515		DELETE
H01L 2224/17517		DELETE
H01L 2224/17519		DELETE
H01L 2224/18		DELETE
H01L 2224/19		DELETE
H01L 2224/20		DELETE
H01L 2224/21		DELETE
H01L 2224/2101		DELETE
H01L 2224/2105		DELETE
H01L 2224/211		DELETE
H01L 2224/214		DELETE
H01L 2224/215		DELETE
H01L 2224/22		DELETE
H01L 2224/2201		DELETE
H01L 2224/2205		DELETE
H01L 2224/221		DELETE
H01L 2224/224		DELETE
H01L 2224/225		DELETE
H01L 2224/22505		DELETE
H01L 2224/23		DELETE
H01L 2224/24		DELETE
H01L 2224/2401		DELETE
H01L 2224/24011		DELETE
H01L 2224/2402		DELETE
H01L 2224/2405		DELETE
H01L 2224/24051		DELETE
H01L 2224/241		DELETE
H01L 2224/24101		DELETE
H01L 2224/24105		DELETE
H01L 2224/2413		DELETE
H01L 2224/24135		DELETE
H01L 2224/24137		DELETE
H01L 2224/24141		DELETE
H01L 2224/24145		DELETE
H01L 2224/24146		DELETE
H01L 2224/24147		DELETE
H01L 2224/24151		DELETE
H01L 2224/24153		DELETE
H01L 2224/24155		DELETE
H01L 2224/24175		DELETE
H01L 2224/24195		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/24221		DELETE
H01L 2224/24225		DELETE
H01L 2224/24226		DELETE
H01L 2224/24227		DELETE
H01L 2224/24245		DELETE
H01L 2224/24246		DELETE
H01L 2224/24247		DELETE
H01L 2224/24265		DELETE
H01L 2224/244		DELETE
H01L 2224/245		DELETE
H01L 2224/2499		DELETE
H01L 2224/24991		DELETE
H01L 2224/24992		DELETE
H01L 2224/24996		DELETE
H01L 2224/24997		DELETE
H01L 2224/24998		DELETE
H01L 2224/25		DELETE
H01L 2224/2501		DELETE
H01L 2224/2505		DELETE
H01L 2224/251		DELETE
H01L 2224/25105		DELETE
H01L 2224/2511		DELETE
H01L 2224/25111		DELETE
H01L 2224/25112		DELETE
H01L 2224/25113		DELETE
H01L 2224/2512		DELETE
H01L 2224/25171		DELETE
H01L 2224/25174		DELETE
H01L 2224/25175		DELETE
H01L 2224/25177		DELETE
H01L 2224/2518		DELETE
H01L 2224/254		DELETE
H01L 2224/2541		DELETE
H01L 2224/2543		DELETE
H01L 2224/255		DELETE
H01L 2224/26		DELETE
H01L 2224/2612		DELETE
H01L 2224/26122		DELETE
H01L 2224/26125		DELETE
H01L 2224/26135		DELETE
H01L 2224/26145		DELETE
H01L 2224/26152		DELETE
H01L 2224/26155		DELETE
H01L 2224/26165		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/26175		DELETE
H01L 2224/27		DELETE
H01L 2224/27001		DELETE
H01L 2224/27002		DELETE
H01L 2224/27003		DELETE
H01L 2224/27005		DELETE
H01L 2224/27009		DELETE
H01L 2224/27011		DELETE
H01L 2224/27013		DELETE
H01L 2224/27015		DELETE
H01L 2224/27019		DELETE
H01L 2224/271		DELETE
H01L 2224/2711		DELETE
H01L 2224/2712		DELETE
H01L 2224/273		DELETE
H01L 2224/2731		DELETE
H01L 2224/27312		DELETE
H01L 2224/27318		DELETE
H01L 2224/2732		DELETE
H01L 2224/2733		DELETE
H01L 2224/27332		DELETE
H01L 2224/27334		DELETE
H01L 2224/274		DELETE
H01L 2224/2741		DELETE
H01L 2224/27416		DELETE
H01L 2224/27418		DELETE
H01L 2224/2742		DELETE
H01L 2224/27422		DELETE
H01L 2224/27424		DELETE
H01L 2224/27426		DELETE
H01L 2224/27428		DELETE
H01L 2224/2743		DELETE
H01L 2224/27436		DELETE
H01L 2224/27438		DELETE
H01L 2224/2744		DELETE
H01L 2224/27442		DELETE
H01L 2224/27444		DELETE
H01L 2224/2745		DELETE
H01L 2224/27452		DELETE
H01L 2224/2746		DELETE
H01L 2224/27462		DELETE
H01L 2224/27464		DELETE
H01L 2224/27466		DELETE
H01L 2224/2747		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/27472		DELETE
H01L 2224/27474		DELETE
H01L 2224/2748		DELETE
H01L 2224/275		DELETE
H01L 2224/27502		DELETE
H01L 2224/27505		DELETE
H01L 2224/2751		DELETE
H01L 2224/27515		DELETE
H01L 2224/2752		DELETE
H01L 2224/27522		DELETE
H01L 2224/27524		DELETE
H01L 2224/27526		DELETE
H01L 2224/2755		DELETE
H01L 2224/27552		DELETE
H01L 2224/27554		DELETE
H01L 2224/276		DELETE
H01L 2224/27602		DELETE
H01L 2224/2761		DELETE
H01L 2224/27612		DELETE
H01L 2224/27614		DELETE
H01L 2224/27616		DELETE
H01L 2224/27618		DELETE
H01L 2224/2762		DELETE
H01L 2224/27622		DELETE
H01L 2224/2763		DELETE
H01L 2224/27632		DELETE
H01L 2224/277		DELETE
H01L 2224/278		DELETE
H01L 2224/2781		DELETE
H01L 2224/2782		DELETE
H01L 2224/27821		DELETE
H01L 2224/27822		DELETE
H01L 2224/27823		DELETE
H01L 2224/27824		DELETE
H01L 2224/27825		DELETE
H01L 2224/27826		DELETE
H01L 2224/27827		DELETE
H01L 2224/2783		DELETE
H01L 2224/27831		DELETE
H01L 2224/2784		DELETE
H01L 2224/27845		DELETE
H01L 2224/27848		DELETE
H01L 2224/27849		DELETE
H01L 2224/279		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/27901		DELETE
H01L 2224/27902		DELETE
H01L 2224/27903		DELETE
H01L 2224/27906		DELETE
H01L 2224/2791		DELETE
H01L 2224/27912		DELETE
H01L 2224/27916		DELETE
H01L 2224/28		DELETE
H01L 2224/28105		DELETE
H01L 2224/29		DELETE
H01L 2224/29001		DELETE
H01L 2224/29005		DELETE
H01L 2224/29006		DELETE
H01L 2224/29007		DELETE
H01L 2224/29008		DELETE
H01L 2224/29009		DELETE
H01L 2224/2901		DELETE
H01L 2224/29011		DELETE
H01L 2224/29012		DELETE
H01L 2224/29013		DELETE
H01L 2224/29014		DELETE
H01L 2224/29015		DELETE
H01L 2224/29016		DELETE
H01L 2224/29017		DELETE
H01L 2224/29018		DELETE
H01L 2224/29019		DELETE
H01L 2224/2902		DELETE
H01L 2224/29021		DELETE
H01L 2224/29022		DELETE
H01L 2224/29023		DELETE
H01L 2224/29024		DELETE
H01L 2224/29025		DELETE
H01L 2224/29026		DELETE
H01L 2224/29027		DELETE
H01L 2224/29028		DELETE
H01L 2224/29034		DELETE
H01L 2224/29035		DELETE
H01L 2224/29036		DELETE
H01L 2224/29075		DELETE
H01L 2224/29076		DELETE
H01L 2224/29078		DELETE
H01L 2224/2908		DELETE
H01L 2224/29082		DELETE
H01L 2224/29083		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/29084		DELETE
H01L 2224/29099		DELETE
H01L 2224/291		DELETE
H01L 2224/29101		DELETE
H01L 2224/29105		DELETE
H01L 2224/29109		DELETE
H01L 2224/29111		DELETE
H01L 2224/29113		DELETE
H01L 2224/29114		DELETE
H01L 2224/29116		DELETE
H01L 2224/29117		DELETE
H01L 2224/29118		DELETE
H01L 2224/2912		DELETE
H01L 2224/29123		DELETE
H01L 2224/29124		DELETE
H01L 2224/29138		DELETE
H01L 2224/29139		DELETE
H01L 2224/29144		DELETE
H01L 2224/29147		DELETE
H01L 2224/29149		DELETE
H01L 2224/29155		DELETE
H01L 2224/29157		DELETE
H01L 2224/2916		DELETE
H01L 2224/29163		DELETE
H01L 2224/29164		DELETE
H01L 2224/29166		DELETE
H01L 2224/29169		DELETE
H01L 2224/2917		DELETE
H01L 2224/29171		DELETE
H01L 2224/29172		DELETE
H01L 2224/29173		DELETE
H01L 2224/29176		DELETE
H01L 2224/29178		DELETE
H01L 2224/29179		DELETE
H01L 2224/2918		DELETE
H01L 2224/29181		DELETE
H01L 2224/29183		DELETE
H01L 2224/29184		DELETE
H01L 2224/29186		DELETE
H01L 2224/29187		DELETE
H01L 2224/29188		DELETE
H01L 2224/2919		DELETE
H01L 2224/29191		DELETE
H01L 2224/29193		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/29194		DELETE
H01L 2224/29195		DELETE
H01L 2224/29198		DELETE
H01L 2224/29199		DELETE
H01L 2224/292		DELETE
H01L 2224/29201		DELETE
H01L 2224/29205		DELETE
H01L 2224/29209		DELETE
H01L 2224/29211		DELETE
H01L 2224/29213		DELETE
H01L 2224/29214		DELETE
H01L 2224/29216		DELETE
H01L 2224/29217		DELETE
H01L 2224/29218		DELETE
H01L 2224/2922		DELETE
H01L 2224/29223		DELETE
H01L 2224/29224		DELETE
H01L 2224/29238		DELETE
H01L 2224/29239		DELETE
H01L 2224/29244		DELETE
H01L 2224/29247		DELETE
H01L 2224/29249		DELETE
H01L 2224/29255		DELETE
H01L 2224/29257		DELETE
H01L 2224/2926		DELETE
H01L 2224/29263		DELETE
H01L 2224/29264		DELETE
H01L 2224/29266		DELETE
H01L 2224/29269		DELETE
H01L 2224/2927		DELETE
H01L 2224/29271		DELETE
H01L 2224/29272		DELETE
H01L 2224/29273		DELETE
H01L 2224/29276		DELETE
H01L 2224/29278		DELETE
H01L 2224/29279		DELETE
H01L 2224/2928		DELETE
H01L 2224/29281		DELETE
H01L 2224/29283		DELETE
H01L 2224/29284		DELETE
H01L 2224/29286		DELETE
H01L 2224/29287		DELETE
H01L 2224/29288		DELETE
H01L 2224/2929		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/29291		DELETE
H01L 2224/29293		DELETE
H01L 2224/29294		DELETE
H01L 2224/29295		DELETE
H01L 2224/29298		DELETE
H01L 2224/29299		DELETE
H01L 2224/293		DELETE
H01L 2224/29301		DELETE
H01L 2224/29305		DELETE
H01L 2224/29309		DELETE
H01L 2224/29311		DELETE
H01L 2224/29313		DELETE
H01L 2224/29314		DELETE
H01L 2224/29316		DELETE
H01L 2224/29317		DELETE
H01L 2224/29318		DELETE
H01L 2224/2932		DELETE
H01L 2224/29323		DELETE
H01L 2224/29324		DELETE
H01L 2224/29338		DELETE
H01L 2224/29339		DELETE
H01L 2224/29344		DELETE
H01L 2224/29347		DELETE
H01L 2224/29349		DELETE
H01L 2224/29355		DELETE
H01L 2224/29357		DELETE
H01L 2224/2936		DELETE
H01L 2224/29363		DELETE
H01L 2224/29364		DELETE
H01L 2224/29366		DELETE
H01L 2224/29369		DELETE
H01L 2224/2937		DELETE
H01L 2224/29371		DELETE
H01L 2224/29372		DELETE
H01L 2224/29373		DELETE
H01L 2224/29376		DELETE
H01L 2224/29378		DELETE
H01L 2224/29379		DELETE
H01L 2224/2938		DELETE
H01L 2224/29381		DELETE
H01L 2224/29383		DELETE
H01L 2224/29384		DELETE
H01L 2224/29386		DELETE
H01L 2224/29387		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/29388		DELETE
H01L 2224/2939		DELETE
H01L 2224/29391		DELETE
H01L 2224/29393		DELETE
H01L 2224/29394		DELETE
H01L 2224/29395		DELETE
H01L 2224/29398		DELETE
H01L 2224/29399		DELETE
H01L 2224/294		DELETE
H01L 2224/29401		DELETE
H01L 2224/29405		DELETE
H01L 2224/29409		DELETE
H01L 2224/29411		DELETE
H01L 2224/29413		DELETE
H01L 2224/29414		DELETE
H01L 2224/29416		DELETE
H01L 2224/29417		DELETE
H01L 2224/29418		DELETE
H01L 2224/2942		DELETE
H01L 2224/29423		DELETE
H01L 2224/29424		DELETE
H01L 2224/29438		DELETE
H01L 2224/29439		DELETE
H01L 2224/29444		DELETE
H01L 2224/29447		DELETE
H01L 2224/29449		DELETE
H01L 2224/29455		DELETE
H01L 2224/29457		DELETE
H01L 2224/2946		DELETE
H01L 2224/29463		DELETE
H01L 2224/29464		DELETE
H01L 2224/29466		DELETE
H01L 2224/29469		DELETE
H01L 2224/2947		DELETE
H01L 2224/29471		DELETE
H01L 2224/29472		DELETE
H01L 2224/29473		DELETE
H01L 2224/29476		DELETE
H01L 2224/29478		DELETE
H01L 2224/29479		DELETE
H01L 2224/2948		DELETE
H01L 2224/29481		DELETE
H01L 2224/29483		DELETE
H01L 2224/29484		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/29486		DELETE
H01L 2224/29487		DELETE
H01L 2224/29488		DELETE
H01L 2224/2949		DELETE
H01L 2224/29491		DELETE
H01L 2224/29493		DELETE
H01L 2224/29494		DELETE
H01L 2224/29495		DELETE
H01L 2224/29498		DELETE
H01L 2224/29499		DELETE
H01L 2224/2954		DELETE
H01L 2224/29541		DELETE
H01L 2224/2955		DELETE
H01L 2224/29551		DELETE
H01L 2224/29552		DELETE
H01L 2224/29553		DELETE
H01L 2224/2956		DELETE
H01L 2224/29561		DELETE
H01L 2224/29562		DELETE
H01L 2224/29563		DELETE
H01L 2224/29564		DELETE
H01L 2224/29565		DELETE
H01L 2224/29566		DELETE
H01L 2224/2957		DELETE
H01L 2224/29575		DELETE
H01L 2224/29576		DELETE
H01L 2224/29578		DELETE
H01L 2224/2958		DELETE
H01L 2224/29582		DELETE
H01L 2224/29583		DELETE
H01L 2224/29584		DELETE
H01L 2224/29599		DELETE
H01L 2224/296		DELETE
H01L 2224/29601		DELETE
H01L 2224/29605		DELETE
H01L 2224/29609		DELETE
H01L 2224/29611		DELETE
H01L 2224/29613		DELETE
H01L 2224/29614		DELETE
H01L 2224/29616		DELETE
H01L 2224/29617		DELETE
H01L 2224/29618		DELETE
H01L 2224/2962		DELETE
H01L 2224/29623		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/29624		DELETE
H01L 2224/29638		DELETE
H01L 2224/29639		DELETE
H01L 2224/29644		DELETE
H01L 2224/29647		DELETE
H01L 2224/29649		DELETE
H01L 2224/29655		DELETE
H01L 2224/29657		DELETE
H01L 2224/2966		DELETE
H01L 2224/29663		DELETE
H01L 2224/29664		DELETE
H01L 2224/29666		DELETE
H01L 2224/29669		DELETE
H01L 2224/2967		DELETE
H01L 2224/29671		DELETE
H01L 2224/29672		DELETE
H01L 2224/29673		DELETE
H01L 2224/29676		DELETE
H01L 2224/29678		DELETE
H01L 2224/29679		DELETE
H01L 2224/2968		DELETE
H01L 2224/29681		DELETE
H01L 2224/29683		DELETE
H01L 2224/29684		DELETE
H01L 2224/29686		DELETE
H01L 2224/29687		DELETE
H01L 2224/29688		DELETE
H01L 2224/2969		DELETE
H01L 2224/29691		DELETE
H01L 2224/29693		DELETE
H01L 2224/29694		DELETE
H01L 2224/29695		DELETE
H01L 2224/29698		DELETE
H01L 2224/29699		DELETE
H01L 2224/297		DELETE
H01L 2224/29701		DELETE
H01L 2224/29705		DELETE
H01L 2224/29709		DELETE
H01L 2224/29711		DELETE
H01L 2224/29713		DELETE
H01L 2224/29714		DELETE
H01L 2224/29716		DELETE
H01L 2224/29717		DELETE
H01L 2224/29718		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/2972		DELETE
H01L 2224/29723		DELETE
H01L 2224/29724		DELETE
H01L 2224/29738		DELETE
H01L 2224/29739		DELETE
H01L 2224/29744		DELETE
H01L 2224/29747		DELETE
H01L 2224/29749		DELETE
H01L 2224/29755		DELETE
H01L 2224/29757		DELETE
H01L 2224/2976		DELETE
H01L 2224/29763		DELETE
H01L 2224/29764		DELETE
H01L 2224/29766		DELETE
H01L 2224/29769		DELETE
H01L 2224/2977		DELETE
H01L 2224/29771		DELETE
H01L 2224/29772		DELETE
H01L 2224/29773		DELETE
H01L 2224/29776		DELETE
H01L 2224/29778		DELETE
H01L 2224/29779		DELETE
H01L 2224/2978		DELETE
H01L 2224/29781		DELETE
H01L 2224/29783		DELETE
H01L 2224/29784		DELETE
H01L 2224/29786		DELETE
H01L 2224/29787		DELETE
H01L 2224/29788		DELETE
H01L 2224/2979		DELETE
H01L 2224/29791		DELETE
H01L 2224/29793		DELETE
H01L 2224/29794		DELETE
H01L 2224/29795		DELETE
H01L 2224/29798		DELETE
H01L 2224/29799		DELETE
H01L 2224/298		DELETE
H01L 2224/29801		DELETE
H01L 2224/29805		DELETE
H01L 2224/29809		DELETE
H01L 2224/29811		DELETE
H01L 2224/29813		DELETE
H01L 2224/29814		DELETE
H01L 2224/29816		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/29817		DELETE
H01L 2224/29818		DELETE
H01L 2224/2982		DELETE
H01L 2224/29823		DELETE
H01L 2224/29824		DELETE
H01L 2224/29838		DELETE
H01L 2224/29839		DELETE
H01L 2224/29844		DELETE
H01L 2224/29847		DELETE
H01L 2224/29849		DELETE
H01L 2224/29855		DELETE
H01L 2224/29857		DELETE
H01L 2224/2986		DELETE
H01L 2224/29863		DELETE
H01L 2224/29864		DELETE
H01L 2224/29866		DELETE
H01L 2224/29869		DELETE
H01L 2224/2987		DELETE
H01L 2224/29871		DELETE
H01L 2224/29872		DELETE
H01L 2224/29873		DELETE
H01L 2224/29876		DELETE
H01L 2224/29878		DELETE
H01L 2224/29879		DELETE
H01L 2224/2988		DELETE
H01L 2224/29881		DELETE
H01L 2224/29883		DELETE
H01L 2224/29884		DELETE
H01L 2224/29886		DELETE
H01L 2224/29887		DELETE
H01L 2224/29888		DELETE
H01L 2224/2989		DELETE
H01L 2224/29891		DELETE
H01L 2224/29893		DELETE
H01L 2224/29894		DELETE
H01L 2224/29895		DELETE
H01L 2224/29898		DELETE
H01L 2224/29899		DELETE
H01L 2224/299		DELETE
H01L 2224/29901		DELETE
H01L 2224/29905		DELETE
H01L 2224/29909		DELETE
H01L 2224/29911		DELETE
H01L 2224/29913		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/29914		DELETE
H01L 2224/29916		DELETE
H01L 2224/29917		DELETE
H01L 2224/29918		DELETE
H01L 2224/2992		DELETE
H01L 2224/29923		DELETE
H01L 2224/29924		DELETE
H01L 2224/29938		DELETE
H01L 2224/29939		DELETE
H01L 2224/29944		DELETE
H01L 2224/29947		DELETE
H01L 2224/29949		DELETE
H01L 2224/29955		DELETE
H01L 2224/29957		DELETE
H01L 2224/2996		DELETE
H01L 2224/29963		DELETE
H01L 2224/29964		DELETE
H01L 2224/29966		DELETE
H01L 2224/29969		DELETE
H01L 2224/2997		DELETE
H01L 2224/29971		DELETE
H01L 2224/29972		DELETE
H01L 2224/29973		DELETE
H01L 2224/29976		DELETE
H01L 2224/29978		DELETE
H01L 2224/29979		DELETE
H01L 2224/2998		DELETE
H01L 2224/29981		DELETE
H01L 2224/29983		DELETE
H01L 2224/29984		DELETE
H01L 2224/29986		DELETE
H01L 2224/29987		DELETE
H01L 2224/29988		DELETE
H01L 2224/2999		DELETE
H01L 2224/29991		DELETE
H01L 2224/29993		DELETE
H01L 2224/29994		DELETE
H01L 2224/29995		DELETE
H01L 2224/29998		DELETE
H01L 2224/29999		DELETE
H01L 2224/30		DELETE
H01L 2224/3001		DELETE
H01L 2224/3003		DELETE
H01L 2224/3005		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/30051		DELETE
H01L 2224/301		DELETE
H01L 2224/30104		DELETE
H01L 2224/3011		DELETE
H01L 2224/3012		DELETE
H01L 2224/3013		DELETE
H01L 2224/30131		DELETE
H01L 2224/30132		DELETE
H01L 2224/30133		DELETE
H01L 2224/30134		DELETE
H01L 2224/30135		DELETE
H01L 2224/30136		DELETE
H01L 2224/3014		DELETE
H01L 2224/30141		DELETE
H01L 2224/30142		DELETE
H01L 2224/30143		DELETE
H01L 2224/30145		DELETE
H01L 2224/30146		DELETE
H01L 2224/3015		DELETE
H01L 2224/30151		DELETE
H01L 2224/30152		DELETE
H01L 2224/30153		DELETE
H01L 2224/30154		DELETE
H01L 2224/30155		DELETE
H01L 2224/30156		DELETE
H01L 2224/3016		DELETE
H01L 2224/30163		DELETE
H01L 2224/30164		DELETE
H01L 2224/30165		DELETE
H01L 2224/30166		DELETE
H01L 2224/30177		DELETE
H01L 2224/30179		DELETE
H01L 2224/3018		DELETE
H01L 2224/30181		DELETE
H01L 2224/30183		DELETE
H01L 2224/305		DELETE
H01L 2224/30505		DELETE
H01L 2224/3051		DELETE
H01L 2224/30515		DELETE
H01L 2224/30517		DELETE
H01L 2224/30519		DELETE
H01L 2224/31		DELETE
H01L 2224/32		DELETE
H01L 2224/3201		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/32012		DELETE
H01L 2224/32013		DELETE
H01L 2224/32014		DELETE
H01L 2224/3205		DELETE
H01L 2224/32052		DELETE
H01L 2224/32053		DELETE
H01L 2224/32054		DELETE
H01L 2224/32055		DELETE
H01L 2224/32056		DELETE
H01L 2224/32057		DELETE
H01L 2224/32058		DELETE
H01L 2224/32059		DELETE
H01L 2224/3207		DELETE
H01L 2224/321		DELETE
H01L 2224/32104		DELETE
H01L 2224/32105		DELETE
H01L 2224/32106		DELETE
H01L 2224/32111		DELETE
H01L 2224/32112		DELETE
H01L 2224/32113		DELETE
H01L 2224/3213		DELETE
H01L 2224/32135		DELETE
H01L 2224/32137		DELETE
H01L 2224/32141		DELETE
H01L 2224/32145		DELETE
H01L 2224/32146		DELETE
H01L 2224/32147		DELETE
H01L 2224/32148		DELETE
H01L 2224/32151		DELETE
H01L 2224/32153		DELETE
H01L 2224/32155		DELETE
H01L 2224/32157		DELETE
H01L 2224/3216		DELETE
H01L 2224/32163		DELETE
H01L 2224/32165		DELETE
H01L 2224/32167		DELETE
H01L 2224/32168		DELETE
H01L 2224/32175		DELETE
H01L 2224/32183		DELETE
H01L 2224/32187		DELETE
H01L 2224/32188		DELETE
H01L 2224/32195		DELETE
H01L 2224/32197		DELETE
H01L 2224/32198		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/32221		DELETE
H01L 2224/32225		DELETE
H01L 2224/32227		DELETE
H01L 2224/3223		DELETE
H01L 2224/32233		DELETE
H01L 2224/32235		DELETE
H01L 2224/32237		DELETE
H01L 2224/32238		DELETE
H01L 2224/3224		DELETE
H01L 2224/32245		DELETE
H01L 2224/32253		DELETE
H01L 2224/32257		DELETE
H01L 2224/32258		DELETE
H01L 2224/3226		DELETE
H01L 2224/32265		DELETE
H01L 2224/32267		DELETE
H01L 2224/32268		DELETE
H01L 2224/325		DELETE
H01L 2224/32501		DELETE
H01L 2224/32502		DELETE
H01L 2224/32503		DELETE
H01L 2224/32505		DELETE
H01L 2224/32506		DELETE
H01L 2224/32507		DELETE
H01L 2224/33		DELETE
H01L 2224/3301		DELETE
H01L 2224/3303		DELETE
H01L 2224/3305		DELETE
H01L 2224/33051		DELETE
H01L 2224/33055		DELETE
H01L 2224/331		DELETE
H01L 2224/33104		DELETE
H01L 2224/33106		DELETE
H01L 2224/33107		DELETE
H01L 2224/3312		DELETE
H01L 2224/3313		DELETE
H01L 2224/33132		DELETE
H01L 2224/33133		DELETE
H01L 2224/33134		DELETE
H01L 2224/33135		DELETE
H01L 2224/3314		DELETE
H01L 2224/33142		DELETE
H01L 2224/33143		DELETE
H01L 2224/33144		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/33145		DELETE
H01L 2224/3315		DELETE
H01L 2224/33151		DELETE
H01L 2224/33152		DELETE
H01L 2224/33153		DELETE
H01L 2224/33154		DELETE
H01L 2224/33155		DELETE
H01L 2224/33156		DELETE
H01L 2224/3316		DELETE
H01L 2224/33163		DELETE
H01L 2224/33164		DELETE
H01L 2224/33165		DELETE
H01L 2224/33177		DELETE
H01L 2224/33179		DELETE
H01L 2224/3318		DELETE
H01L 2224/33181		DELETE
H01L 2224/33183		DELETE
H01L 2224/335		DELETE
H01L 2224/33505		DELETE
H01L 2224/3351		DELETE
H01L 2224/33515		DELETE
H01L 2224/33517		DELETE
H01L 2224/33519		DELETE
H01L 2224/34		DELETE
H01L 2224/35		DELETE
H01L 2224/35001		DELETE
H01L 2224/351		DELETE
H01L 2224/3512		DELETE
H01L 2224/35125		DELETE
H01L 2224/352		DELETE
H01L 2224/3521		DELETE
H01L 2224/355		DELETE
H01L 2224/3551		DELETE
H01L 2224/3552		DELETE
H01L 2224/357		DELETE
H01L 2224/358		DELETE
H01L 2224/3581		DELETE
H01L 2224/3582		DELETE
H01L 2224/35821		DELETE
H01L 2224/35822		DELETE
H01L 2224/35823		DELETE
H01L 2224/35824		DELETE
H01L 2224/35825		DELETE
H01L 2224/35826		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/35827		DELETE
H01L 2224/3583		DELETE
H01L 2224/35831		DELETE
H01L 2224/35847		DELETE
H01L 2224/35848		DELETE
H01L 2224/35985		DELETE
H01L 2224/35986		DELETE
H01L 2224/36		DELETE
H01L 2224/37		DELETE
H01L 2224/37001		DELETE
H01L 2224/37005		DELETE
H01L 2224/3701		DELETE
H01L 2224/37011		DELETE
H01L 2224/37012		DELETE
H01L 2224/37013		DELETE
H01L 2224/3702		DELETE
H01L 2224/37025		DELETE
H01L 2224/37026		DELETE
H01L 2224/37028		DELETE
H01L 2224/3703		DELETE
H01L 2224/37032		DELETE
H01L 2224/37033		DELETE
H01L 2224/37034		DELETE
H01L 2224/37099		DELETE
H01L 2224/371		DELETE
H01L 2224/37101		DELETE
H01L 2224/37105		DELETE
H01L 2224/37109		DELETE
H01L 2224/37111		DELETE
H01L 2224/37113		DELETE
H01L 2224/37114		DELETE
H01L 2224/37116		DELETE
H01L 2224/37117		DELETE
H01L 2224/37118		DELETE
H01L 2224/3712		DELETE
H01L 2224/37123		DELETE
H01L 2224/37124		DELETE
H01L 2224/37138		DELETE
H01L 2224/37139		DELETE
H01L 2224/37144		DELETE
H01L 2224/37147		DELETE
H01L 2224/37149		DELETE
H01L 2224/37155		DELETE
H01L 2224/37157		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/3716		DELETE
H01L 2224/37163		DELETE
H01L 2224/37164		DELETE
H01L 2224/37166		DELETE
H01L 2224/37169		DELETE
H01L 2224/3717		DELETE
H01L 2224/37171		DELETE
H01L 2224/37172		DELETE
H01L 2224/37173		DELETE
H01L 2224/37176		DELETE
H01L 2224/37178		DELETE
H01L 2224/37179		DELETE
H01L 2224/3718		DELETE
H01L 2224/37181		DELETE
H01L 2224/37183		DELETE
H01L 2224/37184		DELETE
H01L 2224/37186		DELETE
H01L 2224/37187		DELETE
H01L 2224/37188		DELETE
H01L 2224/3719		DELETE
H01L 2224/37191		DELETE
H01L 2224/37193		DELETE
H01L 2224/37194		DELETE
H01L 2224/37195		DELETE
H01L 2224/37198		DELETE
H01L 2224/37199		DELETE
H01L 2224/372		DELETE
H01L 2224/37201		DELETE
H01L 2224/37205		DELETE
H01L 2224/37209		DELETE
H01L 2224/37211		DELETE
H01L 2224/37213		DELETE
H01L 2224/37214		DELETE
H01L 2224/37216		DELETE
H01L 2224/37217		DELETE
H01L 2224/37218		DELETE
H01L 2224/3722		DELETE
H01L 2224/37223		DELETE
H01L 2224/37224		DELETE
H01L 2224/37238		DELETE
H01L 2224/37239		DELETE
H01L 2224/37244		DELETE
H01L 2224/37247		DELETE
H01L 2224/37249		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/37255		DELETE
H01L 2224/37257		DELETE
H01L 2224/3726		DELETE
H01L 2224/37263		DELETE
H01L 2224/37264		DELETE
H01L 2224/37266		DELETE
H01L 2224/37269		DELETE
H01L 2224/3727		DELETE
H01L 2224/37271		DELETE
H01L 2224/37272		DELETE
H01L 2224/37273		DELETE
H01L 2224/37276		DELETE
H01L 2224/37278		DELETE
H01L 2224/37279		DELETE
H01L 2224/3728		DELETE
H01L 2224/37281		DELETE
H01L 2224/37283		DELETE
H01L 2224/37284		DELETE
H01L 2224/37286		DELETE
H01L 2224/37287		DELETE
H01L 2224/37288		DELETE
H01L 2224/3729		DELETE
H01L 2224/37291		DELETE
H01L 2224/37293		DELETE
H01L 2224/37294		DELETE
H01L 2224/37295		DELETE
H01L 2224/37298		DELETE
H01L 2224/37299		DELETE
H01L 2224/373		DELETE
H01L 2224/37301		DELETE
H01L 2224/37305		DELETE
H01L 2224/37309		DELETE
H01L 2224/37311		DELETE
H01L 2224/37313		DELETE
H01L 2224/37314		DELETE
H01L 2224/37316		DELETE
H01L 2224/37317		DELETE
H01L 2224/37318		DELETE
H01L 2224/3732		DELETE
H01L 2224/37323		DELETE
H01L 2224/37324		DELETE
H01L 2224/37338		DELETE
H01L 2224/37339		DELETE
H01L 2224/37344		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/37347		DELETE
H01L 2224/37349		DELETE
H01L 2224/37355		DELETE
H01L 2224/37357		DELETE
H01L 2224/3736		DELETE
H01L 2224/37363		DELETE
H01L 2224/37364		DELETE
H01L 2224/37366		DELETE
H01L 2224/37369		DELETE
H01L 2224/3737		DELETE
H01L 2224/37371		DELETE
H01L 2224/37372		DELETE
H01L 2224/37373		DELETE
H01L 2224/37376		DELETE
H01L 2224/37378		DELETE
H01L 2224/37379		DELETE
H01L 2224/3738		DELETE
H01L 2224/37381		DELETE
H01L 2224/37383		DELETE
H01L 2224/37384		DELETE
H01L 2224/37386		DELETE
H01L 2224/37387		DELETE
H01L 2224/37388		DELETE
H01L 2224/3739		DELETE
H01L 2224/37391		DELETE
H01L 2224/37393		DELETE
H01L 2224/37394		DELETE
H01L 2224/37395		DELETE
H01L 2224/37398		DELETE
H01L 2224/37399		DELETE
H01L 2224/374		DELETE
H01L 2224/37401		DELETE
H01L 2224/37405		DELETE
H01L 2224/37409		DELETE
H01L 2224/37411		DELETE
H01L 2224/37413		DELETE
H01L 2224/37414		DELETE
H01L 2224/37416		DELETE
H01L 2224/37417		DELETE
H01L 2224/37418		DELETE
H01L 2224/3742		DELETE
H01L 2224/37423		DELETE
H01L 2224/37424		DELETE
H01L 2224/37438		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/37439		DELETE
H01L 2224/37444		DELETE
H01L 2224/37447		DELETE
H01L 2224/37449		DELETE
H01L 2224/37455		DELETE
H01L 2224/37457		DELETE
H01L 2224/3746		DELETE
H01L 2224/37463		DELETE
H01L 2224/37464		DELETE
H01L 2224/37466		DELETE
H01L 2224/37469		DELETE
H01L 2224/3747		DELETE
H01L 2224/37471		DELETE
H01L 2224/37472		DELETE
H01L 2224/37473		DELETE
H01L 2224/37476		DELETE
H01L 2224/37478		DELETE
H01L 2224/37479		DELETE
H01L 2224/3748		DELETE
H01L 2224/37481		DELETE
H01L 2224/37483		DELETE
H01L 2224/37484		DELETE
H01L 2224/37486		DELETE
H01L 2224/37487		DELETE
H01L 2224/37488		DELETE
H01L 2224/3749		DELETE
H01L 2224/37491		DELETE
H01L 2224/37493		DELETE
H01L 2224/37494		DELETE
H01L 2224/37495		DELETE
H01L 2224/37498		DELETE
H01L 2224/37499		DELETE
H01L 2224/3754		DELETE
H01L 2224/37541		DELETE
H01L 2224/3755		DELETE
H01L 2224/3756		DELETE
H01L 2224/37565		DELETE
H01L 2224/3757		DELETE
H01L 2224/37572		DELETE
H01L 2224/37573		DELETE
H01L 2224/37574		DELETE
H01L 2224/37576		DELETE
H01L 2224/37578		DELETE
H01L 2224/37599		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/376		DELETE
H01L 2224/37601		DELETE
H01L 2224/37605		DELETE
H01L 2224/37609		DELETE
H01L 2224/37611		DELETE
H01L 2224/37613		DELETE
H01L 2224/37614		DELETE
H01L 2224/37616		DELETE
H01L 2224/37617		DELETE
H01L 2224/37618		DELETE
H01L 2224/3762		DELETE
H01L 2224/37623		DELETE
H01L 2224/37624		DELETE
H01L 2224/37638		DELETE
H01L 2224/37639		DELETE
H01L 2224/37644		DELETE
H01L 2224/37647		DELETE
H01L 2224/37649		DELETE
H01L 2224/37655		DELETE
H01L 2224/37657		DELETE
H01L 2224/3766		DELETE
H01L 2224/37663		DELETE
H01L 2224/37664		DELETE
H01L 2224/37666		DELETE
H01L 2224/37669		DELETE
H01L 2224/3767		DELETE
H01L 2224/37671		DELETE
H01L 2224/37672		DELETE
H01L 2224/37673		DELETE
H01L 2224/37676		DELETE
H01L 2224/37678		DELETE
H01L 2224/37679		DELETE
H01L 2224/3768		DELETE
H01L 2224/37681		DELETE
H01L 2224/37683		DELETE
H01L 2224/37684		DELETE
H01L 2224/37686		DELETE
H01L 2224/37687		DELETE
H01L 2224/37688		DELETE
H01L 2224/3769		DELETE
H01L 2224/37691		DELETE
H01L 2224/37693		DELETE
H01L 2224/37694		DELETE
H01L 2224/37695		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/37698		DELETE
H01L 2224/37699		DELETE
H01L 2224/377		DELETE
H01L 2224/37701		DELETE
H01L 2224/37705		DELETE
H01L 2224/37709		DELETE
H01L 2224/37711		DELETE
H01L 2224/37713		DELETE
H01L 2224/37714		DELETE
H01L 2224/37716		DELETE
H01L 2224/37717		DELETE
H01L 2224/37718		DELETE
H01L 2224/3772		DELETE
H01L 2224/37723		DELETE
H01L 2224/37724		DELETE
H01L 2224/37738		DELETE
H01L 2224/37739		DELETE
H01L 2224/37744		DELETE
H01L 2224/37747		DELETE
H01L 2224/37749		DELETE
H01L 2224/37755		DELETE
H01L 2224/37757		DELETE
H01L 2224/3776		DELETE
H01L 2224/37763		DELETE
H01L 2224/37764		DELETE
H01L 2224/37766		DELETE
H01L 2224/37769		DELETE
H01L 2224/3777		DELETE
H01L 2224/37771		DELETE
H01L 2224/37772		DELETE
H01L 2224/37773		DELETE
H01L 2224/37776		DELETE
H01L 2224/37778		DELETE
H01L 2224/37779		DELETE
H01L 2224/3778		DELETE
H01L 2224/37781		DELETE
H01L 2224/37783		DELETE
H01L 2224/37784		DELETE
H01L 2224/37786		DELETE
H01L 2224/37787		DELETE
H01L 2224/37788		DELETE
H01L 2224/3779		DELETE
H01L 2224/37791		DELETE
H01L 2224/37793		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/37794		DELETE
H01L 2224/37795		DELETE
H01L 2224/37798		DELETE
H01L 2224/37799		DELETE
H01L 2224/378		DELETE
H01L 2224/37801		DELETE
H01L 2224/37805		DELETE
H01L 2224/37809		DELETE
H01L 2224/37811		DELETE
H01L 2224/37813		DELETE
H01L 2224/37814		DELETE
H01L 2224/37816		DELETE
H01L 2224/37817		DELETE
H01L 2224/37818		DELETE
H01L 2224/3782		DELETE
H01L 2224/37823		DELETE
H01L 2224/37824		DELETE
H01L 2224/37838		DELETE
H01L 2224/37839		DELETE
H01L 2224/37844		DELETE
H01L 2224/37847		DELETE
H01L 2224/37849		DELETE
H01L 2224/37855		DELETE
H01L 2224/37857		DELETE
H01L 2224/3786		DELETE
H01L 2224/37863		DELETE
H01L 2224/37864		DELETE
H01L 2224/37866		DELETE
H01L 2224/37869		DELETE
H01L 2224/3787		DELETE
H01L 2224/37871		DELETE
H01L 2224/37872		DELETE
H01L 2224/37873		DELETE
H01L 2224/37876		DELETE
H01L 2224/37878		DELETE
H01L 2224/37879		DELETE
H01L 2224/3788		DELETE
H01L 2224/37881		DELETE
H01L 2224/37883		DELETE
H01L 2224/37884		DELETE
H01L 2224/37886		DELETE
H01L 2224/37887		DELETE
H01L 2224/37888		DELETE
H01L 2224/3789		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/37891		DELETE
H01L 2224/37893		DELETE
H01L 2224/37894		DELETE
H01L 2224/37895		DELETE
H01L 2224/37898		DELETE
H01L 2224/37899		DELETE
H01L 2224/379		DELETE
H01L 2224/37901		DELETE
H01L 2224/37905		DELETE
H01L 2224/37909		DELETE
H01L 2224/37911		DELETE
H01L 2224/37913		DELETE
H01L 2224/37914		DELETE
H01L 2224/37916		DELETE
H01L 2224/37917		DELETE
H01L 2224/37918		DELETE
H01L 2224/3792		DELETE
H01L 2224/37923		DELETE
H01L 2224/37924		DELETE
H01L 2224/37938		DELETE
H01L 2224/37939		DELETE
H01L 2224/37944		DELETE
H01L 2224/37947		DELETE
H01L 2224/37949		DELETE
H01L 2224/37955		DELETE
H01L 2224/37957		DELETE
H01L 2224/3796		DELETE
H01L 2224/37963		DELETE
H01L 2224/37964		DELETE
H01L 2224/37966		DELETE
H01L 2224/37969		DELETE
H01L 2224/3797		DELETE
H01L 2224/37971		DELETE
H01L 2224/37972		DELETE
H01L 2224/37973		DELETE
H01L 2224/37976		DELETE
H01L 2224/37978		DELETE
H01L 2224/37979		DELETE
H01L 2224/3798		DELETE
H01L 2224/37981		DELETE
H01L 2224/37983		DELETE
H01L 2224/37984		DELETE
H01L 2224/37986		DELETE
H01L 2224/37987		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/37988		DELETE
H01L 2224/3799		DELETE
H01L 2224/37991		DELETE
H01L 2224/37993		DELETE
H01L 2224/37994		DELETE
H01L 2224/37995		DELETE
H01L 2224/37998		DELETE
H01L 2224/37999		DELETE
H01L 2224/38		DELETE
H01L 2224/39		DELETE
H01L 2224/40		DELETE
H01L 2224/4001		DELETE
H01L 2224/4005		DELETE
H01L 2224/4007		DELETE
H01L 2224/4009		DELETE
H01L 2224/40091		DELETE
H01L 2224/40095		DELETE
H01L 2224/401		DELETE
H01L 2224/40101		DELETE
H01L 2224/40105		DELETE
H01L 2224/40106		DELETE
H01L 2224/40108		DELETE
H01L 2224/40111		DELETE
H01L 2224/4013		DELETE
H01L 2224/40132		DELETE
H01L 2224/40135		DELETE
H01L 2224/40137		DELETE
H01L 2224/40139		DELETE
H01L 2224/40141		DELETE
H01L 2224/40145		DELETE
H01L 2224/40147		DELETE
H01L 2224/40151		DELETE
H01L 2224/40153		DELETE
H01L 2224/40155		DELETE
H01L 2224/40157		DELETE
H01L 2224/40158		DELETE
H01L 2224/40159		DELETE
H01L 2224/4016		DELETE
H01L 2224/40163		DELETE
H01L 2224/40165		DELETE
H01L 2224/40175		DELETE
H01L 2224/40177		DELETE
H01L 2224/40178		DELETE
H01L 2224/40179		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/40183		DELETE
H01L 2224/40195		DELETE
H01L 2224/40221		DELETE
H01L 2224/40225		DELETE
H01L 2224/40227		DELETE
H01L 2224/40228		DELETE
H01L 2224/40229		DELETE
H01L 2224/4023		DELETE
H01L 2224/40233		DELETE
H01L 2224/40235		DELETE
H01L 2224/40237		DELETE
H01L 2224/4024		DELETE
H01L 2224/40245		DELETE
H01L 2224/40247		DELETE
H01L 2224/40248		DELETE
H01L 2224/40249		DELETE
H01L 2224/40253		DELETE
H01L 2224/40257		DELETE
H01L 2224/4026		DELETE
H01L 2224/40265		DELETE
H01L 2224/404		DELETE
H01L 2224/4046		DELETE
H01L 2224/40475		DELETE
H01L 2224/40477		DELETE
H01L 2224/40479		DELETE
H01L 2224/4048		DELETE
H01L 2224/40484		DELETE
H01L 2224/40486		DELETE
H01L 2224/40487		DELETE
H01L 2224/40491		DELETE
H01L 2224/40496		DELETE
H01L 2224/40499		DELETE
H01L 2224/405		DELETE
H01L 2224/40505		DELETE
H01L 2224/40506		DELETE
H01L 2224/40507		DELETE
H01L 2224/4051		DELETE
H01L 2224/4052		DELETE
H01L 2224/4099		DELETE
H01L 2224/40991		DELETE
H01L 2224/40992		DELETE
H01L 2224/40993		DELETE
H01L 2224/40996		DELETE
H01L 2224/40997		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/40998		DELETE
H01L 2224/41		DELETE
H01L 2224/4101		DELETE
H01L 2224/4103		DELETE
H01L 2224/4105		DELETE
H01L 2224/41051		DELETE
H01L 2224/41052		DELETE
H01L 2224/411		DELETE
H01L 2224/41105		DELETE
H01L 2224/41107		DELETE
H01L 2224/41109		DELETE
H01L 2224/4111		DELETE
H01L 2224/41111		DELETE
H01L 2224/41112		DELETE
H01L 2224/41113		DELETE
H01L 2224/4112		DELETE
H01L 2224/4117		DELETE
H01L 2224/41171		DELETE
H01L 2224/41173		DELETE
H01L 2224/41174		DELETE
H01L 2224/41175		DELETE
H01L 2224/41176		DELETE
H01L 2224/41177		DELETE
H01L 2224/41179		DELETE
H01L 2224/4118		DELETE
H01L 2224/414		DELETE
H01L 2224/4141		DELETE
H01L 2224/41421		DELETE
H01L 2224/41422		DELETE
H01L 2224/4143		DELETE
H01L 2224/415		DELETE
H01L 2224/41505		DELETE
H01L 2224/42		DELETE
H01L 2224/43		DELETE
H01L 2224/43001		DELETE
H01L 2224/431		DELETE
H01L 2224/4312		DELETE
H01L 2224/43125		DELETE
H01L 2224/432		DELETE
H01L 2224/4321		DELETE
H01L 2224/435		DELETE
H01L 2224/4351		DELETE
H01L 2224/4352		DELETE
H01L 2224/437		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/438		DELETE
H01L 2224/4381		DELETE
H01L 2224/4382		DELETE
H01L 2224/43821		DELETE
H01L 2224/43822		DELETE
H01L 2224/43823		DELETE
H01L 2224/43824		DELETE
H01L 2224/43825		DELETE
H01L 2224/43826		DELETE
H01L 2224/43827		DELETE
H01L 2224/4383		DELETE
H01L 2224/43831		DELETE
H01L 2224/43847		DELETE
H01L 2224/43848		DELETE
H01L 2224/43985		DELETE
H01L 2224/43986		DELETE
H01L 2224/44		DELETE
H01L 2224/45		DELETE
H01L 2224/45001		DELETE
H01L 2224/45005		DELETE
H01L 2224/4501		DELETE
H01L 2224/45012		DELETE
H01L 2224/45013		DELETE
H01L 2224/45014		DELETE
H01L 2224/45015		DELETE
H01L 2224/45016		DELETE
H01L 2224/4502		DELETE
H01L 2224/45025		DELETE
H01L 2224/45026		DELETE
H01L 2224/45028		DELETE
H01L 2224/4503		DELETE
H01L 2224/45032		DELETE
H01L 2224/45033		DELETE
H01L 2224/45034		DELETE
H01L 2224/45099		DELETE
H01L 2224/451		DELETE
H01L 2224/45101		DELETE
H01L 2224/45105		DELETE
H01L 2224/45109		DELETE
H01L 2224/45111		DELETE
H01L 2224/45113		DELETE
H01L 2224/45114		DELETE
H01L 2224/45116		DELETE
H01L 2224/45117		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/45118		DELETE
H01L 2224/4512		DELETE
H01L 2224/45123		DELETE
H01L 2224/45124		DELETE
H01L 2224/45138		DELETE
H01L 2224/45139		DELETE
H01L 2224/45144		DELETE
H01L 2224/45147		DELETE
H01L 2224/45149		DELETE
H01L 2224/45155		DELETE
H01L 2224/45157		DELETE
H01L 2224/4516		DELETE
H01L 2224/45163		DELETE
H01L 2224/45164		DELETE
H01L 2224/45166		DELETE
H01L 2224/45169		DELETE
H01L 2224/4517		DELETE
H01L 2224/45171		DELETE
H01L 2224/45172		DELETE
H01L 2224/45173		DELETE
H01L 2224/45176		DELETE
H01L 2224/45178		DELETE
H01L 2224/45179		DELETE
H01L 2224/4518		DELETE
H01L 2224/45181		DELETE
H01L 2224/45183		DELETE
H01L 2224/45184		DELETE
H01L 2224/45186		DELETE
H01L 2224/45187		DELETE
H01L 2224/45188		DELETE
H01L 2224/4519		DELETE
H01L 2224/45191		DELETE
H01L 2224/45193		DELETE
H01L 2224/45194		DELETE
H01L 2224/45195		DELETE
H01L 2224/45198		DELETE
H01L 2224/45199		DELETE
H01L 2224/452		DELETE
H01L 2224/45201		DELETE
H01L 2224/45205		DELETE
H01L 2224/45209		DELETE
H01L 2224/45211		DELETE
H01L 2224/45213		DELETE
H01L 2224/45214		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/45216		DELETE
H01L 2224/45217		DELETE
H01L 2224/45218		DELETE
H01L 2224/4522		DELETE
H01L 2224/45223		DELETE
H01L 2224/45224		DELETE
H01L 2224/45238		DELETE
H01L 2224/45239		DELETE
H01L 2224/45244		DELETE
H01L 2224/45247		DELETE
H01L 2224/45249		DELETE
H01L 2224/45255		DELETE
H01L 2224/45257		DELETE
H01L 2224/4526		DELETE
H01L 2224/45263		DELETE
H01L 2224/45264		DELETE
H01L 2224/45266		DELETE
H01L 2224/45269		DELETE
H01L 2224/4527		DELETE
H01L 2224/45271		DELETE
H01L 2224/45272		DELETE
H01L 2224/45273		DELETE
H01L 2224/45276		DELETE
H01L 2224/45278		DELETE
H01L 2224/45279		DELETE
H01L 2224/4528		DELETE
H01L 2224/45281		DELETE
H01L 2224/45283		DELETE
H01L 2224/45284		DELETE
H01L 2224/45286		DELETE
H01L 2224/45287		DELETE
H01L 2224/45288		DELETE
H01L 2224/4529		DELETE
H01L 2224/45291		DELETE
H01L 2224/45293		DELETE
H01L 2224/45294		DELETE
H01L 2224/45295		DELETE
H01L 2224/45298		DELETE
H01L 2224/45299		DELETE
H01L 2224/453		DELETE
H01L 2224/45301		DELETE
H01L 2224/45305		DELETE
H01L 2224/45309		DELETE
H01L 2224/45311		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/45313		DELETE
H01L 2224/45314		DELETE
H01L 2224/45316		DELETE
H01L 2224/45317		DELETE
H01L 2224/45318		DELETE
H01L 2224/4532		DELETE
H01L 2224/45323		DELETE
H01L 2224/45324		DELETE
H01L 2224/45338		DELETE
H01L 2224/45339		DELETE
H01L 2224/45344		DELETE
H01L 2224/45347		DELETE
H01L 2224/45349		DELETE
H01L 2224/45355		DELETE
H01L 2224/45357		DELETE
H01L 2224/4536		DELETE
H01L 2224/45363		DELETE
H01L 2224/45364		DELETE
H01L 2224/45366		DELETE
H01L 2224/45369		DELETE
H01L 2224/4537		DELETE
H01L 2224/45371		DELETE
H01L 2224/45372		DELETE
H01L 2224/45373		DELETE
H01L 2224/45376		DELETE
H01L 2224/45378		DELETE
H01L 2224/45379		DELETE
H01L 2224/4538		DELETE
H01L 2224/45381		DELETE
H01L 2224/45383		DELETE
H01L 2224/45384		DELETE
H01L 2224/45386		DELETE
H01L 2224/45387		DELETE
H01L 2224/45388		DELETE
H01L 2224/4539		DELETE
H01L 2224/45391		DELETE
H01L 2224/45393		DELETE
H01L 2224/45394		DELETE
H01L 2224/45395		DELETE
H01L 2224/45398		DELETE
H01L 2224/45399		DELETE
H01L 2224/454		DELETE
H01L 2224/45401		DELETE
H01L 2224/45405		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/45409		DELETE
H01L 2224/45411		DELETE
H01L 2224/45413		DELETE
H01L 2224/45414		DELETE
H01L 2224/45416		DELETE
H01L 2224/45417		DELETE
H01L 2224/45418		DELETE
H01L 2224/4542		DELETE
H01L 2224/45423		DELETE
H01L 2224/45424		DELETE
H01L 2224/45438		DELETE
H01L 2224/45439		DELETE
H01L 2224/45444		DELETE
H01L 2224/45447		DELETE
H01L 2224/45449		DELETE
H01L 2224/45455		DELETE
H01L 2224/45457		DELETE
H01L 2224/4546		DELETE
H01L 2224/45463		DELETE
H01L 2224/45464		DELETE
H01L 2224/45466		DELETE
H01L 2224/45469		DELETE
H01L 2224/4547		DELETE
H01L 2224/45471		DELETE
H01L 2224/45472		DELETE
H01L 2224/45473		DELETE
H01L 2224/45476		DELETE
H01L 2224/45478		DELETE
H01L 2224/45479		DELETE
H01L 2224/4548		DELETE
H01L 2224/45481		DELETE
H01L 2224/45483		DELETE
H01L 2224/45484		DELETE
H01L 2224/45486		DELETE
H01L 2224/45487		DELETE
H01L 2224/45488		DELETE
H01L 2224/4549		DELETE
H01L 2224/45491		DELETE
H01L 2224/45493		DELETE
H01L 2224/45494		DELETE
H01L 2224/45495		DELETE
H01L 2224/45498		DELETE
H01L 2224/45499		DELETE
H01L 2224/4554		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/45541		DELETE
H01L 2224/4555		DELETE
H01L 2224/4556		DELETE
H01L 2224/45565		DELETE
H01L 2224/4557		DELETE
H01L 2224/45572		DELETE
H01L 2224/45573		DELETE
H01L 2224/45574		DELETE
H01L 2224/45576		DELETE
H01L 2224/45578		DELETE
H01L 2224/45599		DELETE
H01L 2224/456		DELETE
H01L 2224/45601		DELETE
H01L 2224/45605		DELETE
H01L 2224/45609		DELETE
H01L 2224/45611		DELETE
H01L 2224/45613		DELETE
H01L 2224/45614		DELETE
H01L 2224/45616		DELETE
H01L 2224/45617		DELETE
H01L 2224/45618		DELETE
H01L 2224/4562		DELETE
H01L 2224/45623		DELETE
H01L 2224/45624		DELETE
H01L 2224/45638		DELETE
H01L 2224/45639		DELETE
H01L 2224/45644		DELETE
H01L 2224/45647		DELETE
H01L 2224/45649		DELETE
H01L 2224/45655		DELETE
H01L 2224/45657		DELETE
H01L 2224/4566		DELETE
H01L 2224/45663		DELETE
H01L 2224/45664		DELETE
H01L 2224/45666		DELETE
H01L 2224/45669		DELETE
H01L 2224/4567		DELETE
H01L 2224/45671		DELETE
H01L 2224/45672		DELETE
H01L 2224/45673		DELETE
H01L 2224/45676		DELETE
H01L 2224/45678		DELETE
H01L 2224/45679		DELETE
H01L 2224/4568		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/45681		DELETE
H01L 2224/45683		DELETE
H01L 2224/45684		DELETE
H01L 2224/45686		DELETE
H01L 2224/45687		DELETE
H01L 2224/45688		DELETE
H01L 2224/4569		DELETE
H01L 2224/45691		DELETE
H01L 2224/45693		DELETE
H01L 2224/45694		DELETE
H01L 2224/45695		DELETE
H01L 2224/45698		DELETE
H01L 2224/45699		DELETE
H01L 2224/457		DELETE
H01L 2224/45701		DELETE
H01L 2224/45705		DELETE
H01L 2224/45709		DELETE
H01L 2224/45711		DELETE
H01L 2224/45713		DELETE
H01L 2224/45714		DELETE
H01L 2224/45716		DELETE
H01L 2224/45717		DELETE
H01L 2224/45718		DELETE
H01L 2224/4572		DELETE
H01L 2224/45723		DELETE
H01L 2224/45724		DELETE
H01L 2224/45738		DELETE
H01L 2224/45739		DELETE
H01L 2224/45744		DELETE
H01L 2224/45747		DELETE
H01L 2224/45749		DELETE
H01L 2224/45755		DELETE
H01L 2224/45757		DELETE
H01L 2224/4576		DELETE
H01L 2224/45763		DELETE
H01L 2224/45764		DELETE
H01L 2224/45766		DELETE
H01L 2224/45769		DELETE
H01L 2224/4577		DELETE
H01L 2224/45771		DELETE
H01L 2224/45772		DELETE
H01L 2224/45773		DELETE
H01L 2224/45776		DELETE
H01L 2224/45778		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/45779		DELETE
H01L 2224/4578		DELETE
H01L 2224/45781		DELETE
H01L 2224/45783		DELETE
H01L 2224/45784		DELETE
H01L 2224/45786		DELETE
H01L 2224/45787		DELETE
H01L 2224/45788		DELETE
H01L 2224/4579		DELETE
H01L 2224/45791		DELETE
H01L 2224/45793		DELETE
H01L 2224/45794		DELETE
H01L 2224/45795		DELETE
H01L 2224/45798		DELETE
H01L 2224/45799		DELETE
H01L 2224/458		DELETE
H01L 2224/45801		DELETE
H01L 2224/45805		DELETE
H01L 2224/45809		DELETE
H01L 2224/45811		DELETE
H01L 2224/45813		DELETE
H01L 2224/45814		DELETE
H01L 2224/45816		DELETE
H01L 2224/45817		DELETE
H01L 2224/45818		DELETE
H01L 2224/4582		DELETE
H01L 2224/45823		DELETE
H01L 2224/45824		DELETE
H01L 2224/45838		DELETE
H01L 2224/45839		DELETE
H01L 2224/45844		DELETE
H01L 2224/45847		DELETE
H01L 2224/45849		DELETE
H01L 2224/45855		DELETE
H01L 2224/45857		DELETE
H01L 2224/4586		DELETE
H01L 2224/45863		DELETE
H01L 2224/45864		DELETE
H01L 2224/45866		DELETE
H01L 2224/45869		DELETE
H01L 2224/4587		DELETE
H01L 2224/45871		DELETE
H01L 2224/45872		DELETE
H01L 2224/45873		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/45876		DELETE
H01L 2224/45878		DELETE
H01L 2224/45879		DELETE
H01L 2224/4588		DELETE
H01L 2224/45881		DELETE
H01L 2224/45883		DELETE
H01L 2224/45884		DELETE
H01L 2224/45886		DELETE
H01L 2224/45887		DELETE
H01L 2224/45888		DELETE
H01L 2224/4589		DELETE
H01L 2224/45891		DELETE
H01L 2224/45893		DELETE
H01L 2224/45894		DELETE
H01L 2224/45895		DELETE
H01L 2224/45898		DELETE
H01L 2224/45899		DELETE
H01L 2224/459		DELETE
H01L 2224/45901		DELETE
H01L 2224/45905		DELETE
H01L 2224/45909		DELETE
H01L 2224/45911		DELETE
H01L 2224/45913		DELETE
H01L 2224/45914		DELETE
H01L 2224/45916		DELETE
H01L 2224/45917		DELETE
H01L 2224/45918		DELETE
H01L 2224/4592		DELETE
H01L 2224/45923		DELETE
H01L 2224/45924		DELETE
H01L 2224/45938		DELETE
H01L 2224/45939		DELETE
H01L 2224/45944		DELETE
H01L 2224/45947		DELETE
H01L 2224/45949		DELETE
H01L 2224/45955		DELETE
H01L 2224/45957		DELETE
H01L 2224/4596		DELETE
H01L 2224/45963		DELETE
H01L 2224/45964		DELETE
H01L 2224/45966		DELETE
H01L 2224/45969		DELETE
H01L 2224/4597		DELETE
H01L 2224/45971		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/45972		DELETE
H01L 2224/45973		DELETE
H01L 2224/45976		DELETE
H01L 2224/45978		DELETE
H01L 2224/45979		DELETE
H01L 2224/4598		DELETE
H01L 2224/45981		DELETE
H01L 2224/45983		DELETE
H01L 2224/45984		DELETE
H01L 2224/45986		DELETE
H01L 2224/45987		DELETE
H01L 2224/45988		DELETE
H01L 2224/4599		DELETE
H01L 2224/45991		DELETE
H01L 2224/45993		DELETE
H01L 2224/45994		DELETE
H01L 2224/45995		DELETE
H01L 2224/45998		DELETE
H01L 2224/45999		DELETE
H01L 2224/46		DELETE
H01L 2224/47		DELETE
H01L 2224/48		DELETE
H01L 2224/4801		DELETE
H01L 2224/48011		DELETE
H01L 2224/4805		DELETE
H01L 2224/4807		DELETE
H01L 2224/4809		DELETE
H01L 2224/48091		DELETE
H01L 2224/48092		DELETE
H01L 2224/48095		DELETE
H01L 2224/48096		DELETE
H01L 2224/48097		DELETE
H01L 2224/481		DELETE
H01L 2224/48101		DELETE
H01L 2224/48105		DELETE
H01L 2224/48106		DELETE
H01L 2224/48108		DELETE
H01L 2224/4811		DELETE
H01L 2224/48111		DELETE
H01L 2224/4813		DELETE
H01L 2224/48132		DELETE
H01L 2224/48135		DELETE
H01L 2224/48137		DELETE
H01L 2224/48138		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/48139		DELETE
H01L 2224/4814		DELETE
H01L 2224/48141		DELETE
H01L 2224/48145		DELETE
H01L 2224/48147		DELETE
H01L 2224/48148		DELETE
H01L 2224/48149		DELETE
H01L 2224/48151		DELETE
H01L 2224/48153		DELETE
H01L 2224/48155		DELETE
H01L 2224/48157		DELETE
H01L 2224/48158		DELETE
H01L 2224/48159		DELETE
H01L 2224/4816		DELETE
H01L 2224/48163		DELETE
H01L 2224/48165		DELETE
H01L 2224/48175		DELETE
H01L 2224/48177		DELETE
H01L 2224/48178		DELETE
H01L 2224/48179		DELETE
H01L 2224/48183		DELETE
H01L 2224/48195		DELETE
H01L 2224/48221		DELETE
H01L 2224/48225		DELETE
H01L 2224/48227		DELETE
H01L 2224/48228		DELETE
H01L 2224/48229		DELETE
H01L 2224/4823		DELETE
H01L 2224/48233		DELETE
H01L 2224/48235		DELETE
H01L 2224/48237		DELETE
H01L 2224/4824		DELETE
H01L 2224/48245		DELETE
H01L 2224/48247		DELETE
H01L 2224/48248		DELETE
H01L 2224/48249		DELETE
H01L 2224/48253		DELETE
H01L 2224/48257		DELETE
H01L 2224/4826		DELETE
H01L 2224/48265		DELETE
H01L 2224/484		DELETE
H01L 2224/4845		DELETE
H01L 2224/48451		DELETE
H01L 2224/48453		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/48455		DELETE
H01L 2224/48456		DELETE
H01L 2224/48458		DELETE
H01L 2224/4846		DELETE
H01L 2224/48463		DELETE
H01L 2224/48464		DELETE
H01L 2224/48465		DELETE
H01L 2224/4847		DELETE
H01L 2224/48471		DELETE
H01L 2224/48472		DELETE
H01L 2224/48475		DELETE
H01L 2224/48476		DELETE
H01L 2224/48477		DELETE
H01L 2224/48478		DELETE
H01L 2224/48479		DELETE
H01L 2224/4848		DELETE
H01L 2224/48481		DELETE
H01L 2224/48482		DELETE
H01L 2224/48483		DELETE
H01L 2224/48484		DELETE
H01L 2224/48485		DELETE
H01L 2224/48486		DELETE
H01L 2224/48487		DELETE
H01L 2224/48488		DELETE
H01L 2224/48489		DELETE
H01L 2224/4849		DELETE
H01L 2224/48491		DELETE
H01L 2224/48496		DELETE
H01L 2224/48499		DELETE
H01L 2224/485		DELETE
H01L 2224/48505		DELETE
H01L 2224/48506		DELETE
H01L 2224/48507		DELETE
H01L 2224/4851		DELETE
H01L 2224/48511		DELETE
H01L 2224/4852		DELETE
H01L 2224/48599		DELETE
H01L 2224/486		DELETE
H01L 2224/48601		DELETE
H01L 2224/48605		DELETE
H01L 2224/48609		DELETE
H01L 2224/48611		DELETE
H01L 2224/48613		DELETE
H01L 2224/48614		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/48616		DELETE
H01L 2224/48617		DELETE
H01L 2224/48618		DELETE
H01L 2224/4862		DELETE
H01L 2224/48623		DELETE
H01L 2224/48624		DELETE
H01L 2224/48638		DELETE
H01L 2224/48639		DELETE
H01L 2224/48644		DELETE
H01L 2224/48647		DELETE
H01L 2224/48649		DELETE
H01L 2224/48655		DELETE
H01L 2224/48657		DELETE
H01L 2224/4866		DELETE
H01L 2224/48663		DELETE
H01L 2224/48664		DELETE
H01L 2224/48666		DELETE
H01L 2224/48669		DELETE
H01L 2224/4867		DELETE
H01L 2224/48671		DELETE
H01L 2224/48672		DELETE
H01L 2224/48673		DELETE
H01L 2224/48678		DELETE
H01L 2224/48679		DELETE
H01L 2224/4868		DELETE
H01L 2224/48681		DELETE
H01L 2224/48683		DELETE
H01L 2224/48684		DELETE
H01L 2224/48686		DELETE
H01L 2224/48687		DELETE
H01L 2224/48688		DELETE
H01L 2224/4869		DELETE
H01L 2224/48691		DELETE
H01L 2224/48693		DELETE
H01L 2224/48694		DELETE
H01L 2224/48698		DELETE
H01L 2224/48699		DELETE
H01L 2224/487		DELETE
H01L 2224/48701		DELETE
H01L 2224/48705		DELETE
H01L 2224/48709		DELETE
H01L 2224/48711		DELETE
H01L 2224/48713		DELETE
H01L 2224/48714		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/48716		DELETE
H01L 2224/48717		DELETE
H01L 2224/48718		DELETE
H01L 2224/4872		DELETE
H01L 2224/48723		DELETE
H01L 2224/48724		DELETE
H01L 2224/48738		DELETE
H01L 2224/48739		DELETE
H01L 2224/48744		DELETE
H01L 2224/48747		DELETE
H01L 2224/48749		DELETE
H01L 2224/48755		DELETE
H01L 2224/48757		DELETE
H01L 2224/4876		DELETE
H01L 2224/48763		DELETE
H01L 2224/48764		DELETE
H01L 2224/48766		DELETE
H01L 2224/48769		DELETE
H01L 2224/4877		DELETE
H01L 2224/48771		DELETE
H01L 2224/48772		DELETE
H01L 2224/48773		DELETE
H01L 2224/48778		DELETE
H01L 2224/48779		DELETE
H01L 2224/4878		DELETE
H01L 2224/48781		DELETE
H01L 2224/48783		DELETE
H01L 2224/48784		DELETE
H01L 2224/48786		DELETE
H01L 2224/48787		DELETE
H01L 2224/48788		DELETE
H01L 2224/4879		DELETE
H01L 2224/48791		DELETE
H01L 2224/48793		DELETE
H01L 2224/48794		DELETE
H01L 2224/48798		DELETE
H01L 2224/48799		DELETE
H01L 2224/488		DELETE
H01L 2224/48801		DELETE
H01L 2224/48805		DELETE
H01L 2224/48809		DELETE
H01L 2224/48811		DELETE
H01L 2224/48813		DELETE
H01L 2224/48814		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/48816		DELETE
H01L 2224/48817		DELETE
H01L 2224/48818		DELETE
H01L 2224/4882		DELETE
H01L 2224/48823		DELETE
H01L 2224/48824		DELETE
H01L 2224/48838		DELETE
H01L 2224/48839		DELETE
H01L 2224/48844		DELETE
H01L 2224/48847		DELETE
H01L 2224/48849		DELETE
H01L 2224/48855		DELETE
H01L 2224/48857		DELETE
H01L 2224/4886		DELETE
H01L 2224/48863		DELETE
H01L 2224/48864		DELETE
H01L 2224/48866		DELETE
H01L 2224/48869		DELETE
H01L 2224/4887		DELETE
H01L 2224/48871		DELETE
H01L 2224/48872		DELETE
H01L 2224/48873		DELETE
H01L 2224/48878		DELETE
H01L 2224/48879		DELETE
H01L 2224/4888		DELETE
H01L 2224/48881		DELETE
H01L 2224/48883		DELETE
H01L 2224/48884		DELETE
H01L 2224/48886		DELETE
H01L 2224/48887		DELETE
H01L 2224/48888		DELETE
H01L 2224/4889		DELETE
H01L 2224/48891		DELETE
H01L 2224/48893		DELETE
H01L 2224/48894		DELETE
H01L 2224/48898		DELETE
H01L 2224/4899		DELETE
H01L 2224/48991		DELETE
H01L 2224/48992		DELETE
H01L 2224/48993		DELETE
H01L 2224/48996		DELETE
H01L 2224/48997		DELETE
H01L 2224/48998		DELETE
H01L 2224/49		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/4901		DELETE
H01L 2224/4903		DELETE
H01L 2224/4905		DELETE
H01L 2224/49051		DELETE
H01L 2224/49052		DELETE
H01L 2224/4909		DELETE
H01L 2224/49095		DELETE
H01L 2224/49096		DELETE
H01L 2224/49097		DELETE
H01L 2224/491		DELETE
H01L 2224/49105		DELETE
H01L 2224/49107		DELETE
H01L 2224/49109		DELETE
H01L 2224/4911		DELETE
H01L 2224/49111		DELETE
H01L 2224/49112		DELETE
H01L 2224/49113		DELETE
H01L 2224/4912		DELETE
H01L 2224/4917		DELETE
H01L 2224/49171		DELETE
H01L 2224/49173		DELETE
H01L 2224/49174		DELETE
H01L 2224/49175		DELETE
H01L 2224/49176		DELETE
H01L 2224/49177		DELETE
H01L 2224/49179		DELETE
H01L 2224/4918		DELETE
H01L 2224/494		DELETE
H01L 2224/4941		DELETE
H01L 2224/4942		DELETE
H01L 2224/49421		DELETE
H01L 2224/49422		DELETE
H01L 2224/49425		DELETE
H01L 2224/49426		DELETE
H01L 2224/49427		DELETE
H01L 2224/49429		DELETE
H01L 2224/4943		DELETE
H01L 2224/49431		DELETE
H01L 2224/49433		DELETE
H01L 2224/4945		DELETE
H01L 2224/495		DELETE
H01L 2224/49505		DELETE
H01L 2224/50		DELETE
H01L 2224/63		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/64		DELETE
H01L 2224/65		DELETE
H01L 2224/66		DELETE
H01L 2224/67		DELETE
H01L 2224/68		DELETE
H01L 2224/69		DELETE
H01L 2224/70		DELETE
H01L 2224/71		DELETE
H01L 2224/72		DELETE
H01L 2224/73		DELETE
H01L 2224/731		DELETE
H01L 2224/73101		DELETE
H01L 2224/73103		DELETE
H01L 2224/73104		DELETE
H01L 2224/73151		DELETE
H01L 2224/73153		DELETE
H01L 2224/732		DELETE
H01L 2224/73201		DELETE
H01L 2224/73203		DELETE
H01L 2224/73204		DELETE
H01L 2224/73205		DELETE
H01L 2224/73207		DELETE
H01L 2224/73209		DELETE
H01L 2224/73211		DELETE
H01L 2224/73213		DELETE
H01L 2224/73215		DELETE
H01L 2224/73217		DELETE
H01L 2224/73219		DELETE
H01L 2224/73221		DELETE
H01L 2224/73223		DELETE
H01L 2224/73225		DELETE
H01L 2224/73227		DELETE
H01L 2224/73229		DELETE
H01L 2224/73231		DELETE
H01L 2224/73251		DELETE
H01L 2224/73253		DELETE
H01L 2224/73255		DELETE
H01L 2224/73257		DELETE
H01L 2224/73259		DELETE
H01L 2224/73261		DELETE
H01L 2224/73263		DELETE
H01L 2224/73265		DELETE
H01L 2224/73267		DELETE
H01L 2224/73269		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/73271		DELETE
H01L 2224/73273		DELETE
H01L 2224/73275		DELETE
H01L 2224/73277		DELETE
H01L 2224/73279		DELETE
H01L 2224/73281		DELETE
H01L 2224/74		DELETE
H01L 2224/741		DELETE
H01L 2224/742		DELETE
H01L 2224/743		DELETE
H01L 2224/744		DELETE
H01L 2224/745		DELETE
H01L 2224/749		DELETE
H01L 2224/75		DELETE
H01L 2224/75001		DELETE
H01L 2224/7501		DELETE
H01L 2224/751		DELETE
H01L 2224/75101		DELETE
H01L 2224/75102		DELETE
H01L 2224/7511		DELETE
H01L 2224/7515		DELETE
H01L 2224/75151		DELETE
H01L 2224/75152		DELETE
H01L 2224/75153		DELETE
H01L 2224/75155		DELETE
H01L 2224/75158		DELETE
H01L 2224/75161		DELETE
H01L 2224/7517		DELETE
H01L 2224/75171		DELETE
H01L 2224/7518		DELETE
H01L 2224/75181		DELETE
H01L 2224/75182		DELETE
H01L 2224/75183		DELETE
H01L 2224/75184		DELETE
H01L 2224/75185		DELETE
H01L 2224/75186		DELETE
H01L 2224/75187		DELETE
H01L 2224/75188		DELETE
H01L 2224/75189		DELETE
H01L 2224/752		DELETE
H01L 2224/7525		DELETE
H01L 2224/75251		DELETE
H01L 2224/75252		DELETE
H01L 2224/75253		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/7526		DELETE
H01L 2224/75261		DELETE
H01L 2224/75262		DELETE
H01L 2224/75263		DELETE
H01L 2224/75264		DELETE
H01L 2224/75265		DELETE
H01L 2224/75266		DELETE
H01L 2224/75267		DELETE
H01L 2224/75268		DELETE
H01L 2224/75269		DELETE
H01L 2224/7527		DELETE
H01L 2224/75271		DELETE
H01L 2224/75272		DELETE
H01L 2224/7528		DELETE
H01L 2224/75281		DELETE
H01L 2224/75282		DELETE
H01L 2224/75283		DELETE
H01L 2224/753		DELETE
H01L 2224/75301		DELETE
H01L 2224/75302		DELETE
H01L 2224/75303		DELETE
H01L 2224/75304		DELETE
H01L 2224/75305		DELETE
H01L 2224/7531		DELETE
H01L 2224/75312		DELETE
H01L 2224/75313		DELETE
H01L 2224/75314		DELETE
H01L 2224/75315		DELETE
H01L 2224/75316		DELETE
H01L 2224/75317		DELETE
H01L 2224/75318		DELETE
H01L 2224/7532		DELETE
H01L 2224/75343		DELETE
H01L 2224/75344		DELETE
H01L 2224/75345		DELETE
H01L 2224/75346		DELETE
H01L 2224/75347		DELETE
H01L 2224/75348		DELETE
H01L 2224/75349		DELETE
H01L 2224/7535		DELETE
H01L 2224/75351		DELETE
H01L 2224/75352		DELETE
H01L 2224/75353		DELETE
H01L 2224/75354		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/75355		DELETE
H01L 2224/755		DELETE
H01L 2224/75501		DELETE
H01L 2224/75502		DELETE
H01L 2224/7555		DELETE
H01L 2224/756		DELETE
H01L 2224/75601		DELETE
H01L 2224/75611		DELETE
H01L 2224/75621		DELETE
H01L 2224/7565		DELETE
H01L 2224/75651		DELETE
H01L 2224/75652		DELETE
H01L 2224/75653		DELETE
H01L 2224/75654		DELETE
H01L 2224/75655		DELETE
H01L 2224/757		DELETE
H01L 2224/75701		DELETE
H01L 2224/75702		DELETE
H01L 2224/75703		DELETE
H01L 2224/75704		DELETE
H01L 2224/75705		DELETE
H01L 2224/75723		DELETE
H01L 2224/75724		DELETE
H01L 2224/75725		DELETE
H01L 2224/75733		DELETE
H01L 2224/75734		DELETE
H01L 2224/75735		DELETE
H01L 2224/75743		DELETE
H01L 2224/75744		DELETE
H01L 2224/75745		DELETE
H01L 2224/75753		DELETE
H01L 2224/75754		DELETE
H01L 2224/75755		DELETE
H01L 2224/75756		DELETE
H01L 2224/758		DELETE
H01L 2224/75801		DELETE
H01L 2224/75802		DELETE
H01L 2224/75803		DELETE
H01L 2224/75804		DELETE
H01L 2224/75821		DELETE
H01L 2224/75822		DELETE
H01L 2224/75823		DELETE
H01L 2224/75824		DELETE
H01L 2224/75841		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/75842		DELETE
H01L 2224/75843		DELETE
H01L 2224/759		DELETE
H01L 2224/75901		DELETE
H01L 2224/7592		DELETE
H01L 2224/75925		DELETE
H01L 2224/7595		DELETE
H01L 2224/7598		DELETE
H01L 2224/75981		DELETE
H01L 2224/75982		DELETE
H01L 2224/75983		DELETE
H01L 2224/75984		DELETE
H01L 2224/75985		DELETE
H01L 2224/75986		DELETE
H01L 2224/75987		DELETE
H01L 2224/75988		DELETE
H01L 2224/76		DELETE
H01L 2224/76001		DELETE
H01L 2224/7601		DELETE
H01L 2224/761		DELETE
H01L 2224/76101		DELETE
H01L 2224/76102		DELETE
H01L 2224/7611		DELETE
H01L 2224/7615		DELETE
H01L 2224/76151		DELETE
H01L 2224/76152		DELETE
H01L 2224/76155		DELETE
H01L 2224/76158		DELETE
H01L 2224/76161		DELETE
H01L 2224/7617		DELETE
H01L 2224/76171		DELETE
H01L 2224/7618		DELETE
H01L 2224/76181		DELETE
H01L 2224/76182		DELETE
H01L 2224/76183		DELETE
H01L 2224/76184		DELETE
H01L 2224/76185		DELETE
H01L 2224/76186		DELETE
H01L 2224/76187		DELETE
H01L 2224/76188		DELETE
H01L 2224/76189		DELETE
H01L 2224/762		DELETE
H01L 2224/7625		DELETE
H01L 2224/76251		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/76252		DELETE
H01L 2224/76253		DELETE
H01L 2224/7626		DELETE
H01L 2224/76261		DELETE
H01L 2224/76262		DELETE
H01L 2224/76263		DELETE
H01L 2224/76264		DELETE
H01L 2224/76265		DELETE
H01L 2224/76266		DELETE
H01L 2224/76267		DELETE
H01L 2224/76268		DELETE
H01L 2224/76269		DELETE
H01L 2224/7627		DELETE
H01L 2224/76271		DELETE
H01L 2224/76272		DELETE
H01L 2224/7628		DELETE
H01L 2224/76281		DELETE
H01L 2224/76282		DELETE
H01L 2224/76283		DELETE
H01L 2224/763		DELETE
H01L 2224/76301		DELETE
H01L 2224/76302		DELETE
H01L 2224/76303		DELETE
H01L 2224/76304		DELETE
H01L 2224/76305		DELETE
H01L 2224/7631		DELETE
H01L 2224/76312		DELETE
H01L 2224/76313		DELETE
H01L 2224/76314		DELETE
H01L 2224/76315		DELETE
H01L 2224/76316		DELETE
H01L 2224/76317		DELETE
H01L 2224/76318		DELETE
H01L 2224/7632		DELETE
H01L 2224/76343		DELETE
H01L 2224/76344		DELETE
H01L 2224/76345		DELETE
H01L 2224/76346		DELETE
H01L 2224/76347		DELETE
H01L 2224/76348		DELETE
H01L 2224/76349		DELETE
H01L 2224/7635		DELETE
H01L 2224/76351		DELETE
H01L 2224/76352		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/76353		DELETE
H01L 2224/76354		DELETE
H01L 2224/76355		DELETE
H01L 2224/765		DELETE
H01L 2224/76501		DELETE
H01L 2224/76502		DELETE
H01L 2224/7655		DELETE
H01L 2224/76552		DELETE
H01L 2224/76554		DELETE
H01L 2224/766		DELETE
H01L 2224/76601		DELETE
H01L 2224/76611		DELETE
H01L 2224/76621		DELETE
H01L 2224/7665		DELETE
H01L 2224/76651		DELETE
H01L 2224/76652		DELETE
H01L 2224/76653		DELETE
H01L 2224/76654		DELETE
H01L 2224/76655		DELETE
H01L 2224/767		DELETE
H01L 2224/76701		DELETE
H01L 2224/76702		DELETE
H01L 2224/76703		DELETE
H01L 2224/76704		DELETE
H01L 2224/76705		DELETE
H01L 2224/76723		DELETE
H01L 2224/76724		DELETE
H01L 2224/76725		DELETE
H01L 2224/76733		DELETE
H01L 2224/76734		DELETE
H01L 2224/76735		DELETE
H01L 2224/76743		DELETE
H01L 2224/76744		DELETE
H01L 2224/76745		DELETE
H01L 2224/76753		DELETE
H01L 2224/76754		DELETE
H01L 2224/76755		DELETE
H01L 2224/76756		DELETE
H01L 2224/768		DELETE
H01L 2224/76801		DELETE
H01L 2224/76802		DELETE
H01L 2224/76803		DELETE
H01L 2224/76804		DELETE
H01L 2224/76821		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/76822		DELETE
H01L 2224/76823		DELETE
H01L 2224/76824		DELETE
H01L 2224/76841		DELETE
H01L 2224/76842		DELETE
H01L 2224/76843		DELETE
H01L 2224/769		DELETE
H01L 2224/76901		DELETE
H01L 2224/7692		DELETE
H01L 2224/76925		DELETE
H01L 2224/7695		DELETE
H01L 2224/7698		DELETE
H01L 2224/76981		DELETE
H01L 2224/76982		DELETE
H01L 2224/76983		DELETE
H01L 2224/76984		DELETE
H01L 2224/76985		DELETE
H01L 2224/76986		DELETE
H01L 2224/76987		DELETE
H01L 2224/76988		DELETE
H01L 2224/77		DELETE
H01L 2224/77001		DELETE
H01L 2224/7701		DELETE
H01L 2224/771		DELETE
H01L 2224/77101		DELETE
H01L 2224/77102		DELETE
H01L 2224/7711		DELETE
H01L 2224/7715		DELETE
H01L 2224/77151		DELETE
H01L 2224/77152		DELETE
H01L 2224/77153		DELETE
H01L 2224/77155		DELETE
H01L 2224/77158		DELETE
H01L 2224/77161		DELETE
H01L 2224/7717		DELETE
H01L 2224/77171		DELETE
H01L 2224/7718		DELETE
H01L 2224/77181		DELETE
H01L 2224/77182		DELETE
H01L 2224/77183		DELETE
H01L 2224/77184		DELETE
H01L 2224/77185		DELETE
H01L 2224/77186		DELETE
H01L 2224/77187		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/77188		DELETE
H01L 2224/77189		DELETE
H01L 2224/772		DELETE
H01L 2224/7725		DELETE
H01L 2224/77251		DELETE
H01L 2224/77252		DELETE
H01L 2224/77253		DELETE
H01L 2224/7726		DELETE
H01L 2224/77261		DELETE
H01L 2224/77262		DELETE
H01L 2224/77263		DELETE
H01L 2224/77264		DELETE
H01L 2224/77265		DELETE
H01L 2224/77266		DELETE
H01L 2224/77267		DELETE
H01L 2224/77268		DELETE
H01L 2224/77269		DELETE
H01L 2224/7727		DELETE
H01L 2224/77271		DELETE
H01L 2224/77272		DELETE
H01L 2224/7728		DELETE
H01L 2224/77281		DELETE
H01L 2224/77282		DELETE
H01L 2224/77283		DELETE
H01L 2224/773		DELETE
H01L 2224/77313		DELETE
H01L 2224/77314		DELETE
H01L 2224/77315		DELETE
H01L 2224/77316		DELETE
H01L 2224/77317		DELETE
H01L 2224/77318		DELETE
H01L 2224/77319		DELETE
H01L 2224/7732		DELETE
H01L 2224/77321		DELETE
H01L 2224/77325		DELETE
H01L 2224/77326		DELETE
H01L 2224/77327		DELETE
H01L 2224/77328		DELETE
H01L 2224/77343		DELETE
H01L 2224/77344		DELETE
H01L 2224/77345		DELETE
H01L 2224/77346		DELETE
H01L 2224/77347		DELETE
H01L 2224/77348		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/77349		DELETE
H01L 2224/7735		DELETE
H01L 2224/77351		DELETE
H01L 2224/77352		DELETE
H01L 2224/77353		DELETE
H01L 2224/77354		DELETE
H01L 2224/77355		DELETE
H01L 2224/775		DELETE
H01L 2224/77501		DELETE
H01L 2224/77502		DELETE
H01L 2224/7755		DELETE
H01L 2224/776		DELETE
H01L 2224/77601		DELETE
H01L 2224/77611		DELETE
H01L 2224/77621		DELETE
H01L 2224/77631		DELETE
H01L 2224/7765		DELETE
H01L 2224/77651		DELETE
H01L 2224/77652		DELETE
H01L 2224/77653		DELETE
H01L 2224/77654		DELETE
H01L 2224/77655		DELETE
H01L 2224/777		DELETE
H01L 2224/77701		DELETE
H01L 2224/77702		DELETE
H01L 2224/77703		DELETE
H01L 2224/77704		DELETE
H01L 2224/77705		DELETE
H01L 2224/77723		DELETE
H01L 2224/77724		DELETE
H01L 2224/77725		DELETE
H01L 2224/77733		DELETE
H01L 2224/77734		DELETE
H01L 2224/77735		DELETE
H01L 2224/77743		DELETE
H01L 2224/77744		DELETE
H01L 2224/77745		DELETE
H01L 2224/77753		DELETE
H01L 2224/77754		DELETE
H01L 2224/77755		DELETE
H01L 2224/77756		DELETE
H01L 2224/778		DELETE
H01L 2224/77801		DELETE
H01L 2224/77802		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/77803		DELETE
H01L 2224/77804		DELETE
H01L 2224/77821		DELETE
H01L 2224/77822		DELETE
H01L 2224/77823		DELETE
H01L 2224/77824		DELETE
H01L 2224/77841		DELETE
H01L 2224/77842		DELETE
H01L 2224/77843		DELETE
H01L 2224/779		DELETE
H01L 2224/77901		DELETE
H01L 2224/7792		DELETE
H01L 2224/77925		DELETE
H01L 2224/7795		DELETE
H01L 2224/7798		DELETE
H01L 2224/77981		DELETE
H01L 2224/77982		DELETE
H01L 2224/77983		DELETE
H01L 2224/77984		DELETE
H01L 2224/77985		DELETE
H01L 2224/77986		DELETE
H01L 2224/77987		DELETE
H01L 2224/77988		DELETE
H01L 2224/78		DELETE
H01L 2224/78001		DELETE
H01L 2224/7801		DELETE
H01L 2224/781		DELETE
H01L 2224/78101		DELETE
H01L 2224/78102		DELETE
H01L 2224/7811		DELETE
H01L 2224/7815		DELETE
H01L 2224/782		DELETE
H01L 2224/7825		DELETE
H01L 2224/78251		DELETE
H01L 2224/78252		DELETE
H01L 2224/78253		DELETE
H01L 2224/7826		DELETE
H01L 2224/78261		DELETE
H01L 2224/78262		DELETE
H01L 2224/78263		DELETE
H01L 2224/78264		DELETE
H01L 2224/78265		DELETE
H01L 2224/78266		DELETE
H01L 2224/78267		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/78268		DELETE
H01L 2224/78269		DELETE
H01L 2224/7827		DELETE
H01L 2224/78271		DELETE
H01L 2224/78272		DELETE
H01L 2224/7828		DELETE
H01L 2224/78281		DELETE
H01L 2224/78282		DELETE
H01L 2224/78283		DELETE
H01L 2224/783		DELETE
H01L 2224/78301		DELETE
H01L 2224/78302		DELETE
H01L 2224/78303		DELETE
H01L 2224/78304		DELETE
H01L 2224/78305		DELETE
H01L 2224/78306		DELETE
H01L 2224/78307		DELETE
H01L 2224/78308		DELETE
H01L 2224/78309		DELETE
H01L 2224/7831		DELETE
H01L 2224/78311		DELETE
H01L 2224/78312		DELETE
H01L 2224/78313		DELETE
H01L 2224/78314		DELETE
H01L 2224/78315		DELETE
H01L 2224/78316		DELETE
H01L 2224/78317		DELETE
H01L 2224/78318		DELETE
H01L 2224/78319		DELETE
H01L 2224/7832		DELETE
H01L 2224/78321		DELETE
H01L 2224/78325		DELETE
H01L 2224/78326		DELETE
H01L 2224/78327		DELETE
H01L 2224/78328		DELETE
H01L 2224/78343		DELETE
H01L 2224/78344		DELETE
H01L 2224/78345		DELETE
H01L 2224/78346		DELETE
H01L 2224/78347		DELETE
H01L 2224/78348		DELETE
H01L 2224/78349		DELETE
H01L 2224/7835		DELETE
H01L 2224/78351		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/78352		DELETE
H01L 2224/78353		DELETE
H01L 2224/78354		DELETE
H01L 2224/78355		DELETE
H01L 2224/785		DELETE
H01L 2224/78501		DELETE
H01L 2224/78502		DELETE
H01L 2224/7855		DELETE
H01L 2224/786		DELETE
H01L 2224/78601		DELETE
H01L 2224/78611		DELETE
H01L 2224/78621		DELETE
H01L 2224/78631		DELETE
H01L 2224/7865		DELETE
H01L 2224/78651		DELETE
H01L 2224/78652		DELETE
H01L 2224/78653		DELETE
H01L 2224/78654		DELETE
H01L 2224/78655		DELETE
H01L 2224/787		DELETE
H01L 2224/78701		DELETE
H01L 2224/78702		DELETE
H01L 2224/78703		DELETE
H01L 2224/78704		DELETE
H01L 2224/78705		DELETE
H01L 2224/78723		DELETE
H01L 2224/78724		DELETE
H01L 2224/78725		DELETE
H01L 2224/78733		DELETE
H01L 2224/78734		DELETE
H01L 2224/78735		DELETE
H01L 2224/78743		DELETE
H01L 2224/78744		DELETE
H01L 2224/78745		DELETE
H01L 2224/78753		DELETE
H01L 2224/78754		DELETE
H01L 2224/78755		DELETE
H01L 2224/78756		DELETE
H01L 2224/788		DELETE
H01L 2224/78801		DELETE
H01L 2224/78802		DELETE
H01L 2224/78803		DELETE
H01L 2224/78804		DELETE
H01L 2224/78821		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/78822		DELETE
H01L 2224/78823		DELETE
H01L 2224/78824		DELETE
H01L 2224/78841		DELETE
H01L 2224/78842		DELETE
H01L 2224/78843		DELETE
H01L 2224/789		DELETE
H01L 2224/78901		DELETE
H01L 2224/7892		DELETE
H01L 2224/78925		DELETE
H01L 2224/7895		DELETE
H01L 2224/7898		DELETE
H01L 2224/78981		DELETE
H01L 2224/78982		DELETE
H01L 2224/78983		DELETE
H01L 2224/78984		DELETE
H01L 2224/78985		DELETE
H01L 2224/78986		DELETE
H01L 2224/78987		DELETE
H01L 2224/78988		DELETE
H01L 2224/79		DELETE
H01L 2224/79001		DELETE
H01L 2224/7901		DELETE
H01L 2224/791		DELETE
H01L 2224/79101		DELETE
H01L 2224/79102		DELETE
H01L 2224/7911		DELETE
H01L 2224/7915		DELETE
H01L 2224/79151		DELETE
H01L 2224/79152		DELETE
H01L 2224/79153		DELETE
H01L 2224/79155		DELETE
H01L 2224/79158		DELETE
H01L 2224/79161		DELETE
H01L 2224/7917		DELETE
H01L 2224/79171		DELETE
H01L 2224/7918		DELETE
H01L 2224/79181		DELETE
H01L 2224/79182		DELETE
H01L 2224/79183		DELETE
H01L 2224/79184		DELETE
H01L 2224/79185		DELETE
H01L 2224/79186		DELETE
H01L 2224/79187		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/79188		DELETE
H01L 2224/79189		DELETE
H01L 2224/792		DELETE
H01L 2224/7925		DELETE
H01L 2224/79251		DELETE
H01L 2224/79252		DELETE
H01L 2224/79253		DELETE
H01L 2224/7926		DELETE
H01L 2224/79261		DELETE
H01L 2224/79262		DELETE
H01L 2224/79263		DELETE
H01L 2224/79264		DELETE
H01L 2224/79265		DELETE
H01L 2224/79266		DELETE
H01L 2224/79267		DELETE
H01L 2224/79268		DELETE
H01L 2224/79269		DELETE
H01L 2224/7927		DELETE
H01L 2224/79271		DELETE
H01L 2224/79272		DELETE
H01L 2224/7928		DELETE
H01L 2224/79281		DELETE
H01L 2224/79282		DELETE
H01L 2224/79283		DELETE
H01L 2224/793		DELETE
H01L 2224/79301		DELETE
H01L 2224/79302		DELETE
H01L 2224/79303		DELETE
H01L 2224/79304		DELETE
H01L 2224/79305		DELETE
H01L 2224/7931		DELETE
H01L 2224/79312		DELETE
H01L 2224/79313		DELETE
H01L 2224/79314		DELETE
H01L 2224/79315		DELETE
H01L 2224/79316		DELETE
H01L 2224/79317		DELETE
H01L 2224/79318		DELETE
H01L 2224/7932		DELETE
H01L 2224/79343		DELETE
H01L 2224/79344		DELETE
H01L 2224/79345		DELETE
H01L 2224/79346		DELETE
H01L 2224/79347		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/79348		DELETE
H01L 2224/79349		DELETE
H01L 2224/7935		DELETE
H01L 2224/79351		DELETE
H01L 2224/79352		DELETE
H01L 2224/79353		DELETE
H01L 2224/79354		DELETE
H01L 2224/79355		DELETE
H01L 2224/795		DELETE
H01L 2224/79501		DELETE
H01L 2224/79502		DELETE
H01L 2224/7955		DELETE
H01L 2224/796		DELETE
H01L 2224/79601		DELETE
H01L 2224/79611		DELETE
H01L 2224/79621		DELETE
H01L 2224/7965		DELETE
H01L 2224/79651		DELETE
H01L 2224/79652		DELETE
H01L 2224/79653		DELETE
H01L 2224/79654		DELETE
H01L 2224/79655		DELETE
H01L 2224/797		DELETE
H01L 2224/79701		DELETE
H01L 2224/79702		DELETE
H01L 2224/79703		DELETE
H01L 2224/79704		DELETE
H01L 2224/79705		DELETE
H01L 2224/79723		DELETE
H01L 2224/79724		DELETE
H01L 2224/79725		DELETE
H01L 2224/79733		DELETE
H01L 2224/79734		DELETE
H01L 2224/79735		DELETE
H01L 2224/79743		DELETE
H01L 2224/79744		DELETE
H01L 2224/79745		DELETE
H01L 2224/79753		DELETE
H01L 2224/79754		DELETE
H01L 2224/79755		DELETE
H01L 2224/79756		DELETE
H01L 2224/798		DELETE
H01L 2224/79801		DELETE
H01L 2224/79802		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/79803		DELETE
H01L 2224/79804		DELETE
H01L 2224/79821		DELETE
H01L 2224/79822		DELETE
H01L 2224/79823		DELETE
H01L 2224/79824		DELETE
H01L 2224/79841		DELETE
H01L 2224/79842		DELETE
H01L 2224/79843		DELETE
H01L 2224/799		DELETE
H01L 2224/79901		DELETE
H01L 2224/7992		DELETE
H01L 2224/79925		DELETE
H01L 2224/7995		DELETE
H01L 2224/7998		DELETE
H01L 2224/79981		DELETE
H01L 2224/79982		DELETE
H01L 2224/79983		DELETE
H01L 2224/79984		DELETE
H01L 2224/79985		DELETE
H01L 2224/79986		DELETE
H01L 2224/79987		DELETE
H01L 2224/79988		DELETE
H01L 2224/7999		DELETE
H01L 2224/80		DELETE
H01L 2224/80001		DELETE
H01L 2224/80003		DELETE
H01L 2224/80004		DELETE
H01L 2224/80006		DELETE
H01L 2224/80007		DELETE
H01L 2224/80009		DELETE
H01L 2224/8001		DELETE
H01L 2224/80011		DELETE
H01L 2224/80012		DELETE
H01L 2224/80013		DELETE
H01L 2224/80014		DELETE
H01L 2224/80019		DELETE
H01L 2224/8002		DELETE
H01L 2224/80024		DELETE
H01L 2224/8003		DELETE
H01L 2224/80031		DELETE
H01L 2224/80035		DELETE
H01L 2224/80037		DELETE
H01L 2224/80039		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/80041		DELETE
H01L 2224/80047		DELETE
H01L 2224/80048		DELETE
H01L 2224/80051		DELETE
H01L 2224/80052		DELETE
H01L 2224/80053		DELETE
H01L 2224/80054		DELETE
H01L 2224/80055		DELETE
H01L 2224/80065		DELETE
H01L 2224/80075		DELETE
H01L 2224/80085		DELETE
H01L 2224/8009		DELETE
H01L 2224/80091		DELETE
H01L 2224/80092		DELETE
H01L 2224/80093		DELETE
H01L 2224/80095		DELETE
H01L 2224/80096		DELETE
H01L 2224/80097		DELETE
H01L 2224/80098		DELETE
H01L 2224/80099		DELETE
H01L 2224/8011		DELETE
H01L 2224/8012		DELETE
H01L 2224/80121		DELETE
H01L 2224/80122		DELETE
H01L 2224/80123		DELETE
H01L 2224/80125		DELETE
H01L 2224/80127		DELETE
H01L 2224/80129		DELETE
H01L 2224/8013		DELETE
H01L 2224/80132		DELETE
H01L 2224/80136		DELETE
H01L 2224/80138		DELETE
H01L 2224/80139		DELETE
H01L 2224/8014		DELETE
H01L 2224/80141		DELETE
H01L 2224/80143		DELETE
H01L 2224/80148		DELETE
H01L 2224/80149		DELETE
H01L 2224/8015		DELETE
H01L 2224/8016		DELETE
H01L 2224/80169		DELETE
H01L 2224/8017		DELETE
H01L 2224/8018		DELETE
H01L 2224/8019		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/80194		DELETE
H01L 2224/802		DELETE
H01L 2224/80201		DELETE
H01L 2224/80203		DELETE
H01L 2224/80204		DELETE
H01L 2224/80205		DELETE
H01L 2224/80206		DELETE
H01L 2224/80207		DELETE
H01L 2224/80209		DELETE
H01L 2224/80211		DELETE
H01L 2224/80213		DELETE
H01L 2224/80215		DELETE
H01L 2224/8022		DELETE
H01L 2224/80222		DELETE
H01L 2224/80224		DELETE
H01L 2224/8023		DELETE
H01L 2224/80232		DELETE
H01L 2224/80234		DELETE
H01L 2224/80236		DELETE
H01L 2224/80237		DELETE
H01L 2224/80238		DELETE
H01L 2224/8034		DELETE
H01L 2224/80345		DELETE
H01L 2224/80355		DELETE
H01L 2224/80357		DELETE
H01L 2224/80359		DELETE
H01L 2224/8036		DELETE
H01L 2224/80365		DELETE
H01L 2224/80375		DELETE
H01L 2224/80379		DELETE
H01L 2224/8038		DELETE
H01L 2224/80385		DELETE
H01L 2224/80395		DELETE
H01L 2224/80399		DELETE
H01L 2224/804		DELETE
H01L 2224/80401		DELETE
H01L 2224/80405		DELETE
H01L 2224/80409		DELETE
H01L 2224/80411		DELETE
H01L 2224/80413		DELETE
H01L 2224/80414		DELETE
H01L 2224/80416		DELETE
H01L 2224/80417		DELETE
H01L 2224/80418		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/8042		DELETE
H01L 2224/80423		DELETE
H01L 2224/80424		DELETE
H01L 2224/80438		DELETE
H01L 2224/80439		DELETE
H01L 2224/80444		DELETE
H01L 2224/80447		DELETE
H01L 2224/80449		DELETE
H01L 2224/80455		DELETE
H01L 2224/80457		DELETE
H01L 2224/8046		DELETE
H01L 2224/80463		DELETE
H01L 2224/80464		DELETE
H01L 2224/80466		DELETE
H01L 2224/80469		DELETE
H01L 2224/8047		DELETE
H01L 2224/80471		DELETE
H01L 2224/80472		DELETE
H01L 2224/80473		DELETE
H01L 2224/80476		DELETE
H01L 2224/80478		DELETE
H01L 2224/80479		DELETE
H01L 2224/8048		DELETE
H01L 2224/80481		DELETE
H01L 2224/80483		DELETE
H01L 2224/80484		DELETE
H01L 2224/80486		DELETE
H01L 2224/80487		DELETE
H01L 2224/80488		DELETE
H01L 2224/8049		DELETE
H01L 2224/80491		DELETE
H01L 2224/80493		DELETE
H01L 2224/80494		DELETE
H01L 2224/80495		DELETE
H01L 2224/80498		DELETE
H01L 2224/80499		DELETE
H01L 2224/805		DELETE
H01L 2224/80501		DELETE
H01L 2224/80505		DELETE
H01L 2224/80509		DELETE
H01L 2224/80511		DELETE
H01L 2224/80513		DELETE
H01L 2224/80514		DELETE
H01L 2224/80516		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/80517		DELETE
H01L 2224/80518		DELETE
H01L 2224/8052		DELETE
H01L 2224/80523		DELETE
H01L 2224/80524		DELETE
H01L 2224/80538		DELETE
H01L 2224/80539		DELETE
H01L 2224/80544		DELETE
H01L 2224/80547		DELETE
H01L 2224/80549		DELETE
H01L 2224/80555		DELETE
H01L 2224/80557		DELETE
H01L 2224/8056		DELETE
H01L 2224/80563		DELETE
H01L 2224/80564		DELETE
H01L 2224/80566		DELETE
H01L 2224/80569		DELETE
H01L 2224/8057		DELETE
H01L 2224/80571		DELETE
H01L 2224/80572		DELETE
H01L 2224/80573		DELETE
H01L 2224/80576		DELETE
H01L 2224/80578		DELETE
H01L 2224/80579		DELETE
H01L 2224/8058		DELETE
H01L 2224/80581		DELETE
H01L 2224/80583		DELETE
H01L 2224/80584		DELETE
H01L 2224/80586		DELETE
H01L 2224/80587		DELETE
H01L 2224/80588		DELETE
H01L 2224/8059		DELETE
H01L 2224/80591		DELETE
H01L 2224/80593		DELETE
H01L 2224/80594		DELETE
H01L 2224/80595		DELETE
H01L 2224/80598		DELETE
H01L 2224/80599		DELETE
H01L 2224/806		DELETE
H01L 2224/80601		DELETE
H01L 2224/80605		DELETE
H01L 2224/80609		DELETE
H01L 2224/80611		DELETE
H01L 2224/80613		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/80614		DELETE
H01L 2224/80616		DELETE
H01L 2224/80617		DELETE
H01L 2224/80618		DELETE
H01L 2224/8062		DELETE
H01L 2224/80623		DELETE
H01L 2224/80624		DELETE
H01L 2224/80638		DELETE
H01L 2224/80639		DELETE
H01L 2224/80644		DELETE
H01L 2224/80647		DELETE
H01L 2224/80649		DELETE
H01L 2224/80655		DELETE
H01L 2224/80657		DELETE
H01L 2224/8066		DELETE
H01L 2224/80663		DELETE
H01L 2224/80664		DELETE
H01L 2224/80666		DELETE
H01L 2224/80669		DELETE
H01L 2224/8067		DELETE
H01L 2224/80671		DELETE
H01L 2224/80672		DELETE
H01L 2224/80673		DELETE
H01L 2224/80676		DELETE
H01L 2224/80678		DELETE
H01L 2224/80679		DELETE
H01L 2224/8068		DELETE
H01L 2224/80681		DELETE
H01L 2224/80683		DELETE
H01L 2224/80684		DELETE
H01L 2224/80686		DELETE
H01L 2224/80687		DELETE
H01L 2224/80688		DELETE
H01L 2224/8069		DELETE
H01L 2224/80691		DELETE
H01L 2224/80693		DELETE
H01L 2224/80694		DELETE
H01L 2224/80695		DELETE
H01L 2224/80698		DELETE
H01L 2224/80699		DELETE
H01L 2224/807		DELETE
H01L 2224/80701		DELETE
H01L 2224/80705		DELETE
H01L 2224/80709		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/80711		DELETE
H01L 2224/80713		DELETE
H01L 2224/80714		DELETE
H01L 2224/80716		DELETE
H01L 2224/80717		DELETE
H01L 2224/80718		DELETE
H01L 2224/8072		DELETE
H01L 2224/80723		DELETE
H01L 2224/80724		DELETE
H01L 2224/80738		DELETE
H01L 2224/80739		DELETE
H01L 2224/80744		DELETE
H01L 2224/80747		DELETE
H01L 2224/80749		DELETE
H01L 2224/80755		DELETE
H01L 2224/80757		DELETE
H01L 2224/8076		DELETE
H01L 2224/80763		DELETE
H01L 2224/80764		DELETE
H01L 2224/80766		DELETE
H01L 2224/80769		DELETE
H01L 2224/8077		DELETE
H01L 2224/80771		DELETE
H01L 2224/80772		DELETE
H01L 2224/80773		DELETE
H01L 2224/80776		DELETE
H01L 2224/80778		DELETE
H01L 2224/80779		DELETE
H01L 2224/8078		DELETE
H01L 2224/80781		DELETE
H01L 2224/80783		DELETE
H01L 2224/80784		DELETE
H01L 2224/80786		DELETE
H01L 2224/80787		DELETE
H01L 2224/80788		DELETE
H01L 2224/8079		DELETE
H01L 2224/80791		DELETE
H01L 2224/80793		DELETE
H01L 2224/80794		DELETE
H01L 2224/80795		DELETE
H01L 2224/80798		DELETE
H01L 2224/80799		DELETE
H01L 2224/808		DELETE
H01L 2224/80801		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/80805		DELETE
H01L 2224/8081		DELETE
H01L 2224/80815		DELETE
H01L 2224/8082		DELETE
H01L 2224/80825		DELETE
H01L 2224/8083		DELETE
H01L 2224/8084		DELETE
H01L 2224/8085		DELETE
H01L 2224/80855		DELETE
H01L 2224/80856		DELETE
H01L 2224/80859		DELETE
H01L 2224/80862		DELETE
H01L 2224/80865		DELETE
H01L 2224/80868		DELETE
H01L 2224/80871		DELETE
H01L 2224/80874		DELETE
H01L 2224/80877		DELETE
H01L 2224/8088		DELETE
H01L 2224/80885		DELETE
H01L 2224/8089		DELETE
H01L 2224/80893		DELETE
H01L 2224/80894		DELETE
H01L 2224/80895		DELETE
H01L 2224/80896		DELETE
H01L 2224/80897		DELETE
H01L 2224/80898		DELETE
H01L 2224/80899		DELETE
H01L 2224/809		DELETE
H01L 2224/80901		DELETE
H01L 2224/80902		DELETE
H01L 2224/80903		DELETE
H01L 2224/80904		DELETE
H01L 2224/80905		DELETE
H01L 2224/80906		DELETE
H01L 2224/80907		DELETE
H01L 2224/80908		DELETE
H01L 2224/80909		DELETE
H01L 2224/8091		DELETE
H01L 2224/80911		DELETE
H01L 2224/80912		DELETE
H01L 2224/80913		DELETE
H01L 2224/80914		DELETE
H01L 2224/80919		DELETE
H01L 2224/8092		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/8093		DELETE
H01L 2224/80931		DELETE
H01L 2224/80935		DELETE
H01L 2224/80937		DELETE
H01L 2224/80939		DELETE
H01L 2224/80941		DELETE
H01L 2224/80943		DELETE
H01L 2224/80945		DELETE
H01L 2224/80947		DELETE
H01L 2224/80948		DELETE
H01L 2224/80951		DELETE
H01L 2224/80986		DELETE
H01L 2224/81		DELETE
H01L 2224/81001		DELETE
H01L 2224/81002		DELETE
H01L 2224/81005		DELETE
H01L 2224/81007		DELETE
H01L 2224/81009		DELETE
H01L 2224/8101		DELETE
H01L 2224/81011		DELETE
H01L 2224/81012		DELETE
H01L 2224/81013		DELETE
H01L 2224/81014		DELETE
H01L 2224/81019		DELETE
H01L 2224/8102		DELETE
H01L 2224/81022		DELETE
H01L 2224/81024		DELETE
H01L 2224/81026		DELETE
H01L 2224/8103		DELETE
H01L 2224/81031		DELETE
H01L 2224/81035		DELETE
H01L 2224/81037		DELETE
H01L 2224/81039		DELETE
H01L 2224/81041		DELETE
H01L 2224/81047		DELETE
H01L 2224/81048		DELETE
H01L 2224/81051		DELETE
H01L 2224/81052		DELETE
H01L 2224/81053		DELETE
H01L 2224/81054		DELETE
H01L 2224/81055		DELETE
H01L 2224/81065		DELETE
H01L 2224/81075		DELETE
H01L 2224/81085		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/8109		DELETE
H01L 2224/81091		DELETE
H01L 2224/81092		DELETE
H01L 2224/81093		DELETE
H01L 2224/81095		DELETE
H01L 2224/81096		DELETE
H01L 2224/81097		DELETE
H01L 2224/81098		DELETE
H01L 2224/81099		DELETE
H01L 2224/811		DELETE
H01L 2224/81101		DELETE
H01L 2224/8111		DELETE
H01L 2224/8112		DELETE
H01L 2224/81121		DELETE
H01L 2224/81122		DELETE
H01L 2224/81123		DELETE
H01L 2224/81125		DELETE
H01L 2224/81127		DELETE
H01L 2224/81129		DELETE
H01L 2224/8113		DELETE
H01L 2224/81132		DELETE
H01L 2224/81136		DELETE
H01L 2224/81138		DELETE
H01L 2224/81139		DELETE
H01L 2224/8114		DELETE
H01L 2224/81141		DELETE
H01L 2224/81143		DELETE
H01L 2224/81148		DELETE
H01L 2224/81149		DELETE
H01L 2224/8115		DELETE
H01L 2224/8116		DELETE
H01L 2224/81169		DELETE
H01L 2224/8117		DELETE
H01L 2224/8118		DELETE
H01L 2224/8119		DELETE
H01L 2224/81191		DELETE
H01L 2224/81192		DELETE
H01L 2224/81193		DELETE
H01L 2224/81194		DELETE
H01L 2224/812		DELETE
H01L 2224/81201		DELETE
H01L 2224/81203		DELETE
H01L 2224/81204		DELETE
H01L 2224/81205		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/81206		DELETE
H01L 2224/81207		DELETE
H01L 2224/81208		DELETE
H01L 2224/81209		DELETE
H01L 2224/8121		DELETE
H01L 2224/81211		DELETE
H01L 2224/8122		DELETE
H01L 2224/81222		DELETE
H01L 2224/81224		DELETE
H01L 2224/8123		DELETE
H01L 2224/81232		DELETE
H01L 2224/81234		DELETE
H01L 2224/81236		DELETE
H01L 2224/81237		DELETE
H01L 2224/81238		DELETE
H01L 2224/8134		DELETE
H01L 2224/81345		DELETE
H01L 2224/81355		DELETE
H01L 2224/81359		DELETE
H01L 2224/8136		DELETE
H01L 2224/81365		DELETE
H01L 2224/81375		DELETE
H01L 2224/81379		DELETE
H01L 2224/8138		DELETE
H01L 2224/81385		DELETE
H01L 2224/81395		DELETE
H01L 2224/81399		DELETE
H01L 2224/814		DELETE
H01L 2224/81401		DELETE
H01L 2224/81405		DELETE
H01L 2224/81409		DELETE
H01L 2224/81411		DELETE
H01L 2224/81413		DELETE
H01L 2224/81414		DELETE
H01L 2224/81416		DELETE
H01L 2224/81417		DELETE
H01L 2224/81418		DELETE
H01L 2224/8142		DELETE
H01L 2224/81423		DELETE
H01L 2224/81424		DELETE
H01L 2224/81438		DELETE
H01L 2224/81439		DELETE
H01L 2224/81444		DELETE
H01L 2224/81447		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/81449		DELETE
H01L 2224/81455		DELETE
H01L 2224/81457		DELETE
H01L 2224/8146		DELETE
H01L 2224/81463		DELETE
H01L 2224/81464		DELETE
H01L 2224/81466		DELETE
H01L 2224/81469		DELETE
H01L 2224/8147		DELETE
H01L 2224/81471		DELETE
H01L 2224/81472		DELETE
H01L 2224/81473		DELETE
H01L 2224/81476		DELETE
H01L 2224/81478		DELETE
H01L 2224/81479		DELETE
H01L 2224/8148		DELETE
H01L 2224/81481		DELETE
H01L 2224/81483		DELETE
H01L 2224/81484		DELETE
H01L 2224/81486		DELETE
H01L 2224/81487		DELETE
H01L 2224/81488		DELETE
H01L 2224/8149		DELETE
H01L 2224/81491		DELETE
H01L 2224/81493		DELETE
H01L 2224/81494		DELETE
H01L 2224/81495		DELETE
H01L 2224/81498		DELETE
H01L 2224/81499		DELETE
H01L 2224/815		DELETE
H01L 2224/81501		DELETE
H01L 2224/81505		DELETE
H01L 2224/81509		DELETE
H01L 2224/81511		DELETE
H01L 2224/81513		DELETE
H01L 2224/81514		DELETE
H01L 2224/81516		DELETE
H01L 2224/81517		DELETE
H01L 2224/81518		DELETE
H01L 2224/8152		DELETE
H01L 2224/81523		DELETE
H01L 2224/81524		DELETE
H01L 2224/81538		DELETE
H01L 2224/81539		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/81544		DELETE
H01L 2224/81547		DELETE
H01L 2224/81549		DELETE
H01L 2224/81555		DELETE
H01L 2224/81557		DELETE
H01L 2224/8156		DELETE
H01L 2224/81563		DELETE
H01L 2224/81564		DELETE
H01L 2224/81566		DELETE
H01L 2224/81569		DELETE
H01L 2224/8157		DELETE
H01L 2224/81571		DELETE
H01L 2224/81572		DELETE
H01L 2224/81573		DELETE
H01L 2224/81576		DELETE
H01L 2224/81578		DELETE
H01L 2224/81579		DELETE
H01L 2224/8158		DELETE
H01L 2224/81581		DELETE
H01L 2224/81583		DELETE
H01L 2224/81584		DELETE
H01L 2224/81586		DELETE
H01L 2224/81587		DELETE
H01L 2224/81588		DELETE
H01L 2224/8159		DELETE
H01L 2224/81591		DELETE
H01L 2224/81593		DELETE
H01L 2224/81594		DELETE
H01L 2224/81595		DELETE
H01L 2224/81598		DELETE
H01L 2224/81599		DELETE
H01L 2224/816		DELETE
H01L 2224/81601		DELETE
H01L 2224/81605		DELETE
H01L 2224/81609		DELETE
H01L 2224/81611		DELETE
H01L 2224/81613		DELETE
H01L 2224/81614		DELETE
H01L 2224/81616		DELETE
H01L 2224/81617		DELETE
H01L 2224/81618		DELETE
H01L 2224/8162		DELETE
H01L 2224/81623		DELETE
H01L 2224/81624		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/81638		DELETE
H01L 2224/81639		DELETE
H01L 2224/81644		DELETE
H01L 2224/81647		DELETE
H01L 2224/81649		DELETE
H01L 2224/81655		DELETE
H01L 2224/81657		DELETE
H01L 2224/8166		DELETE
H01L 2224/81663		DELETE
H01L 2224/81664		DELETE
H01L 2224/81666		DELETE
H01L 2224/81669		DELETE
H01L 2224/8167		DELETE
H01L 2224/81671		DELETE
H01L 2224/81672		DELETE
H01L 2224/81673		DELETE
H01L 2224/81676		DELETE
H01L 2224/81678		DELETE
H01L 2224/81679		DELETE
H01L 2224/8168		DELETE
H01L 2224/81681		DELETE
H01L 2224/81683		DELETE
H01L 2224/81684		DELETE
H01L 2224/81686		DELETE
H01L 2224/81687		DELETE
H01L 2224/81688		DELETE
H01L 2224/8169		DELETE
H01L 2224/81691		DELETE
H01L 2224/81693		DELETE
H01L 2224/81694		DELETE
H01L 2224/81695		DELETE
H01L 2224/81698		DELETE
H01L 2224/81699		DELETE
H01L 2224/817		DELETE
H01L 2224/81701		DELETE
H01L 2224/81705		DELETE
H01L 2224/81709		DELETE
H01L 2224/81711		DELETE
H01L 2224/81713		DELETE
H01L 2224/81714		DELETE
H01L 2224/81716		DELETE
H01L 2224/81717		DELETE
H01L 2224/81718		DELETE
H01L 2224/8172		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/81723		DELETE
H01L 2224/81724		DELETE
H01L 2224/81738		DELETE
H01L 2224/81739		DELETE
H01L 2224/81744		DELETE
H01L 2224/81747		DELETE
H01L 2224/81749		DELETE
H01L 2224/81755		DELETE
H01L 2224/81757		DELETE
H01L 2224/8176		DELETE
H01L 2224/81763		DELETE
H01L 2224/81764		DELETE
H01L 2224/81766		DELETE
H01L 2224/81769		DELETE
H01L 2224/8177		DELETE
H01L 2224/81771		DELETE
H01L 2224/81772		DELETE
H01L 2224/81773		DELETE
H01L 2224/81776		DELETE
H01L 2224/81778		DELETE
H01L 2224/81779		DELETE
H01L 2224/8178		DELETE
H01L 2224/81781		DELETE
H01L 2224/81783		DELETE
H01L 2224/81784		DELETE
H01L 2224/81786		DELETE
H01L 2224/81787		DELETE
H01L 2224/81788		DELETE
H01L 2224/8179		DELETE
H01L 2224/81791		DELETE
H01L 2224/81793		DELETE
H01L 2224/81794		DELETE
H01L 2224/81795		DELETE
H01L 2224/81798		DELETE
H01L 2224/81799		DELETE
H01L 2224/818		DELETE
H01L 2224/81801		DELETE
H01L 2224/81805		DELETE
H01L 2224/8181		DELETE
H01L 2224/81815		DELETE
H01L 2224/8182		DELETE
H01L 2224/81825		DELETE
H01L 2224/8183		DELETE
H01L 2224/8184		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/8185		DELETE
H01L 2224/81855		DELETE
H01L 2224/81856		DELETE
H01L 2224/81859		DELETE
H01L 2224/81862		DELETE
H01L 2224/81865		DELETE
H01L 2224/81868		DELETE
H01L 2224/81871		DELETE
H01L 2224/81874		DELETE
H01L 2224/81877		DELETE
H01L 2224/8188		DELETE
H01L 2224/81885		DELETE
H01L 2224/8189		DELETE
H01L 2224/81893		DELETE
H01L 2224/81894		DELETE
H01L 2224/81895		DELETE
H01L 2224/81896		DELETE
H01L 2224/81897		DELETE
H01L 2224/81898		DELETE
H01L 2224/81899		DELETE
H01L 2224/819		DELETE
H01L 2224/81901		DELETE
H01L 2224/81902		DELETE
H01L 2224/81903		DELETE
H01L 2224/81904		DELETE
H01L 2224/81905		DELETE
H01L 2224/81906		DELETE
H01L 2224/81907		DELETE
H01L 2224/81908		DELETE
H01L 2224/81909		DELETE
H01L 2224/8191		DELETE
H01L 2224/81911		DELETE
H01L 2224/81912		DELETE
H01L 2224/81913		DELETE
H01L 2224/81914		DELETE
H01L 2224/81919		DELETE
H01L 2224/8192		DELETE
H01L 2224/8193		DELETE
H01L 2224/81931		DELETE
H01L 2224/81935		DELETE
H01L 2224/81937		DELETE
H01L 2224/81939		DELETE
H01L 2224/81941		DELETE
H01L 2224/81943		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/81945		DELETE
H01L 2224/81947		DELETE
H01L 2224/81948		DELETE
H01L 2224/81951		DELETE
H01L 2224/81986		DELETE
H01L 2224/82		DELETE
H01L 2224/82001		DELETE
H01L 2224/82002		DELETE
H01L 2224/82005		DELETE
H01L 2224/82007		DELETE
H01L 2224/82009		DELETE
H01L 2224/8201		DELETE
H01L 2224/8203		DELETE
H01L 2224/82031		DELETE
H01L 2224/82035		DELETE
H01L 2224/82039		DELETE
H01L 2224/82045		DELETE
H01L 2224/82047		DELETE
H01L 2224/82048		DELETE
H01L 2224/82051		DELETE
H01L 2224/82053		DELETE
H01L 2224/82054		DELETE
H01L 2224/82085		DELETE
H01L 2224/8209		DELETE
H01L 2224/82091		DELETE
H01L 2224/82095		DELETE
H01L 2224/82096		DELETE
H01L 2224/82097		DELETE
H01L 2224/82098		DELETE
H01L 2224/82099		DELETE
H01L 2224/821		DELETE
H01L 2224/82101		DELETE
H01L 2224/82102		DELETE
H01L 2224/82103		DELETE
H01L 2224/82104		DELETE
H01L 2224/82105		DELETE
H01L 2224/82106		DELETE
H01L 2224/82108		DELETE
H01L 2224/8211		DELETE
H01L 2224/8212		DELETE
H01L 2224/82121		DELETE
H01L 2224/82122		DELETE
H01L 2224/8213		DELETE
H01L 2224/82132		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/82136		DELETE
H01L 2224/82138		DELETE
H01L 2224/82143		DELETE
H01L 2224/82148		DELETE
H01L 2224/82149		DELETE
H01L 2224/8215		DELETE
H01L 2224/8216		DELETE
H01L 2224/82169		DELETE
H01L 2224/8217		DELETE
H01L 2224/8218		DELETE
H01L 2224/82181		DELETE
H01L 2224/82186		DELETE
H01L 2224/82191		DELETE
H01L 2224/822		DELETE
H01L 2224/82201		DELETE
H01L 2224/82203		DELETE
H01L 2224/82205		DELETE
H01L 2224/82207		DELETE
H01L 2224/8221		DELETE
H01L 2224/82212		DELETE
H01L 2224/82214		DELETE
H01L 2224/8223		DELETE
H01L 2224/82232		DELETE
H01L 2224/82234		DELETE
H01L 2224/82236		DELETE
H01L 2224/82237		DELETE
H01L 2224/82238		DELETE
H01L 2224/8234		DELETE
H01L 2224/82345		DELETE
H01L 2224/82355		DELETE
H01L 2224/82359		DELETE
H01L 2224/8236		DELETE
H01L 2224/82365		DELETE
H01L 2224/82375		DELETE
H01L 2224/82379		DELETE
H01L 2224/8238		DELETE
H01L 2224/82385		DELETE
H01L 2224/82395		DELETE
H01L 2224/82399		DELETE
H01L 2224/828		DELETE
H01L 2224/82801		DELETE
H01L 2224/82805		DELETE
H01L 2224/8281		DELETE
H01L 2224/82815		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/8282		DELETE
H01L 2224/82825		DELETE
H01L 2224/8283		DELETE
H01L 2224/8284		DELETE
H01L 2224/8285		DELETE
H01L 2224/82855		DELETE
H01L 2224/82856		DELETE
H01L 2224/82859		DELETE
H01L 2224/82862		DELETE
H01L 2224/82865		DELETE
H01L 2224/82868		DELETE
H01L 2224/82871		DELETE
H01L 2224/82874		DELETE
H01L 2224/82877		DELETE
H01L 2224/8288		DELETE
H01L 2224/82885		DELETE
H01L 2224/8289		DELETE
H01L 2224/82893		DELETE
H01L 2224/82895		DELETE
H01L 2224/82896		DELETE
H01L 2224/82897		DELETE
H01L 2224/82899		DELETE
H01L 2224/829		DELETE
H01L 2224/82909		DELETE
H01L 2224/8291		DELETE
H01L 2224/8293		DELETE
H01L 2224/82931		DELETE
H01L 2224/82935		DELETE
H01L 2224/82939		DELETE
H01L 2224/82945		DELETE
H01L 2224/82947		DELETE
H01L 2224/82948		DELETE
H01L 2224/82951		DELETE
H01L 2224/82986		DELETE
H01L 2224/83		DELETE
H01L 2224/83001		DELETE
H01L 2224/83002		DELETE
H01L 2224/83005		DELETE
H01L 2224/83007		DELETE
H01L 2224/83009		DELETE
H01L 2224/8301		DELETE
H01L 2224/83011		DELETE
H01L 2224/83012		DELETE
H01L 2224/83013		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/83014		DELETE
H01L 2224/83019		DELETE
H01L 2224/8302		DELETE
H01L 2224/83022		DELETE
H01L 2224/83024		DELETE
H01L 2224/83026		DELETE
H01L 2224/8303		DELETE
H01L 2224/83031		DELETE
H01L 2224/83035		DELETE
H01L 2224/83037		DELETE
H01L 2224/83039		DELETE
H01L 2224/83041		DELETE
H01L 2224/83047		DELETE
H01L 2224/83048		DELETE
H01L 2224/83051		DELETE
H01L 2224/83052		DELETE
H01L 2224/83053		DELETE
H01L 2224/83054		DELETE
H01L 2224/83055		DELETE
H01L 2224/83065		DELETE
H01L 2224/83075		DELETE
H01L 2224/83085		DELETE
H01L 2224/8309		DELETE
H01L 2224/83091		DELETE
H01L 2224/83092		DELETE
H01L 2224/83093		DELETE
H01L 2224/83095		DELETE
H01L 2224/83096		DELETE
H01L 2224/83097		DELETE
H01L 2224/83098		DELETE
H01L 2224/83099		DELETE
H01L 2224/831		DELETE
H01L 2224/83101		DELETE
H01L 2224/83102		DELETE
H01L 2224/83104		DELETE
H01L 2224/8311		DELETE
H01L 2224/8312		DELETE
H01L 2224/83121		DELETE
H01L 2224/83122		DELETE
H01L 2224/83123		DELETE
H01L 2224/83125		DELETE
H01L 2224/83127		DELETE
H01L 2224/83129		DELETE
H01L 2224/8313		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/83132		DELETE
H01L 2224/83136		DELETE
H01L 2224/83138		DELETE
H01L 2224/83139		DELETE
H01L 2224/8314		DELETE
H01L 2224/83141		DELETE
H01L 2224/83143		DELETE
H01L 2224/83148		DELETE
H01L 2224/83149		DELETE
H01L 2224/8315		DELETE
H01L 2224/8316		DELETE
H01L 2224/83169		DELETE
H01L 2224/8317		DELETE
H01L 2224/8318		DELETE
H01L 2224/8319		DELETE
H01L 2224/83191		DELETE
H01L 2224/83192		DELETE
H01L 2224/83193		DELETE
H01L 2224/83194		DELETE
H01L 2224/832		DELETE
H01L 2224/83201		DELETE
H01L 2224/83203		DELETE
H01L 2224/83204		DELETE
H01L 2224/83205		DELETE
H01L 2224/83206		DELETE
H01L 2224/83207		DELETE
H01L 2224/83208		DELETE
H01L 2224/83209		DELETE
H01L 2224/8321		DELETE
H01L 2224/83211		DELETE
H01L 2224/8322		DELETE
H01L 2224/83222		DELETE
H01L 2224/83224		DELETE
H01L 2224/8323		DELETE
H01L 2224/83232		DELETE
H01L 2224/83234		DELETE
H01L 2224/83236		DELETE
H01L 2224/83237		DELETE
H01L 2224/83238		DELETE
H01L 2224/8334		DELETE
H01L 2224/83345		DELETE
H01L 2224/83355		DELETE
H01L 2224/83359		DELETE
H01L 2224/8336		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/83365		DELETE
H01L 2224/83375		DELETE
H01L 2224/83379		DELETE
H01L 2224/8338		DELETE
H01L 2224/83385		DELETE
H01L 2224/83395		DELETE
H01L 2224/83399		DELETE
H01L 2224/834		DELETE
H01L 2224/83401		DELETE
H01L 2224/83405		DELETE
H01L 2224/83409		DELETE
H01L 2224/83411		DELETE
H01L 2224/83413		DELETE
H01L 2224/83414		DELETE
H01L 2224/83416		DELETE
H01L 2224/83417		DELETE
H01L 2224/83418		DELETE
H01L 2224/8342		DELETE
H01L 2224/83423		DELETE
H01L 2224/83424		DELETE
H01L 2224/83438		DELETE
H01L 2224/83439		DELETE
H01L 2224/83444		DELETE
H01L 2224/83447		DELETE
H01L 2224/83449		DELETE
H01L 2224/83455		DELETE
H01L 2224/83457		DELETE
H01L 2224/8346		DELETE
H01L 2224/83463		DELETE
H01L 2224/83464		DELETE
H01L 2224/83466		DELETE
H01L 2224/83469		DELETE
H01L 2224/8347		DELETE
H01L 2224/83471		DELETE
H01L 2224/83472		DELETE
H01L 2224/83473		DELETE
H01L 2224/83476		DELETE
H01L 2224/83478		DELETE
H01L 2224/83479		DELETE
H01L 2224/8348		DELETE
H01L 2224/83481		DELETE
H01L 2224/83483		DELETE
H01L 2224/83484		DELETE
H01L 2224/83486		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/83487		DELETE
H01L 2224/83488		DELETE
H01L 2224/8349		DELETE
H01L 2224/83491		DELETE
H01L 2224/83493		DELETE
H01L 2224/83494		DELETE
H01L 2224/83495		DELETE
H01L 2224/83498		DELETE
H01L 2224/83499		DELETE
H01L 2224/835		DELETE
H01L 2224/83501		DELETE
H01L 2224/83505		DELETE
H01L 2224/83509		DELETE
H01L 2224/83511		DELETE
H01L 2224/83513		DELETE
H01L 2224/83514		DELETE
H01L 2224/83516		DELETE
H01L 2224/83517		DELETE
H01L 2224/83518		DELETE
H01L 2224/8352		DELETE
H01L 2224/83523		DELETE
H01L 2224/83524		DELETE
H01L 2224/83538		DELETE
H01L 2224/83539		DELETE
H01L 2224/83544		DELETE
H01L 2224/83547		DELETE
H01L 2224/83549		DELETE
H01L 2224/83555		DELETE
H01L 2224/83557		DELETE
H01L 2224/8356		DELETE
H01L 2224/83563		DELETE
H01L 2224/83564		DELETE
H01L 2224/83566		DELETE
H01L 2224/83569		DELETE
H01L 2224/8357		DELETE
H01L 2224/83571		DELETE
H01L 2224/83572		DELETE
H01L 2224/83573		DELETE
H01L 2224/83576		DELETE
H01L 2224/83578		DELETE
H01L 2224/83579		DELETE
H01L 2224/8358		DELETE
H01L 2224/83581		DELETE
H01L 2224/83583		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/83584		DELETE
H01L 2224/83586		DELETE
H01L 2224/83587		DELETE
H01L 2224/83588		DELETE
H01L 2224/8359		DELETE
H01L 2224/83591		DELETE
H01L 2224/83593		DELETE
H01L 2224/83594		DELETE
H01L 2224/83595		DELETE
H01L 2224/83598		DELETE
H01L 2224/83599		DELETE
H01L 2224/836		DELETE
H01L 2224/83601		DELETE
H01L 2224/83605		DELETE
H01L 2224/83609		DELETE
H01L 2224/83611		DELETE
H01L 2224/83613		DELETE
H01L 2224/83614		DELETE
H01L 2224/83616		DELETE
H01L 2224/83617		DELETE
H01L 2224/83618		DELETE
H01L 2224/8362		DELETE
H01L 2224/83623		DELETE
H01L 2224/83624		DELETE
H01L 2224/83638		DELETE
H01L 2224/83639		DELETE
H01L 2224/83644		DELETE
H01L 2224/83647		DELETE
H01L 2224/83649		DELETE
H01L 2224/83655		DELETE
H01L 2224/83657		DELETE
H01L 2224/8366		DELETE
H01L 2224/83663		DELETE
H01L 2224/83664		DELETE
H01L 2224/83666		DELETE
H01L 2224/83669		DELETE
H01L 2224/8367		DELETE
H01L 2224/83671		DELETE
H01L 2224/83672		DELETE
H01L 2224/83673		DELETE
H01L 2224/83676		DELETE
H01L 2224/83678		DELETE
H01L 2224/83679		DELETE
H01L 2224/8368		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/83681		DELETE
H01L 2224/83683		DELETE
H01L 2224/83684		DELETE
H01L 2224/83686		DELETE
H01L 2224/83687		DELETE
H01L 2224/83688		DELETE
H01L 2224/8369		DELETE
H01L 2224/83691		DELETE
H01L 2224/83693		DELETE
H01L 2224/83694		DELETE
H01L 2224/83695		DELETE
H01L 2224/83698		DELETE
H01L 2224/83699		DELETE
H01L 2224/837		DELETE
H01L 2224/83701		DELETE
H01L 2224/83705		DELETE
H01L 2224/83709		DELETE
H01L 2224/83711		DELETE
H01L 2224/83713		DELETE
H01L 2224/83714		DELETE
H01L 2224/83716		DELETE
H01L 2224/83717		DELETE
H01L 2224/83718		DELETE
H01L 2224/8372		DELETE
H01L 2224/83723		DELETE
H01L 2224/83724		DELETE
H01L 2224/83738		DELETE
H01L 2224/83739		DELETE
H01L 2224/83744		DELETE
H01L 2224/83747		DELETE
H01L 2224/83749		DELETE
H01L 2224/83755		DELETE
H01L 2224/83757		DELETE
H01L 2224/8376		DELETE
H01L 2224/83763		DELETE
H01L 2224/83764		DELETE
H01L 2224/83766		DELETE
H01L 2224/83769		DELETE
H01L 2224/8377		DELETE
H01L 2224/83771		DELETE
H01L 2224/83772		DELETE
H01L 2224/83773		DELETE
H01L 2224/83776		DELETE
H01L 2224/83778		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/83779		DELETE
H01L 2224/8378		DELETE
H01L 2224/83781		DELETE
H01L 2224/83783		DELETE
H01L 2224/83784		DELETE
H01L 2224/83786		DELETE
H01L 2224/83787		DELETE
H01L 2224/83788		DELETE
H01L 2224/8379		DELETE
H01L 2224/83791		DELETE
H01L 2224/83793		DELETE
H01L 2224/83794		DELETE
H01L 2224/83795		DELETE
H01L 2224/83798		DELETE
H01L 2224/83799		DELETE
H01L 2224/838		DELETE
H01L 2224/83801		DELETE
H01L 2224/83805		DELETE
H01L 2224/8381		DELETE
H01L 2224/83815		DELETE
H01L 2224/8382		DELETE
H01L 2224/83825		DELETE
H01L 2224/8383		DELETE
H01L 2224/8384		DELETE
H01L 2224/8385		DELETE
H01L 2224/83851		DELETE
H01L 2224/83855		DELETE
H01L 2224/83856		DELETE
H01L 2224/83859		DELETE
H01L 2224/83862		DELETE
H01L 2224/83865		DELETE
H01L 2224/83868		DELETE
H01L 2224/83871		DELETE
H01L 2224/83874		DELETE
H01L 2224/83877		DELETE
H01L 2224/8388		DELETE
H01L 2224/83885		DELETE
H01L 2224/83886		DELETE
H01L 2224/83887		DELETE
H01L 2224/83888		DELETE
H01L 2224/83889		DELETE
H01L 2224/8389		DELETE
H01L 2224/83893		DELETE
H01L 2224/83894		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/83895		DELETE
H01L 2224/83896		DELETE
H01L 2224/83897		DELETE
H01L 2224/83898		DELETE
H01L 2224/83899		DELETE
H01L 2224/839		DELETE
H01L 2224/83901		DELETE
H01L 2224/83902		DELETE
H01L 2224/83903		DELETE
H01L 2224/83904		DELETE
H01L 2224/83905		DELETE
H01L 2224/83906		DELETE
H01L 2224/83907		DELETE
H01L 2224/83908		DELETE
H01L 2224/83909		DELETE
H01L 2224/8391		DELETE
H01L 2224/83911		DELETE
H01L 2224/83912		DELETE
H01L 2224/83913		DELETE
H01L 2224/83914		DELETE
H01L 2224/83919		DELETE
H01L 2224/8392		DELETE
H01L 2224/8393		DELETE
H01L 2224/83931		DELETE
H01L 2224/83935		DELETE
H01L 2224/83937		DELETE
H01L 2224/83939		DELETE
H01L 2224/83941		DELETE
H01L 2224/83943		DELETE
H01L 2224/83945		DELETE
H01L 2224/83947		DELETE
H01L 2224/83948		DELETE
H01L 2224/83951		DELETE
H01L 2224/83986		DELETE
H01L 2224/84		DELETE
H01L 2224/84001		DELETE
H01L 2224/84002		DELETE
H01L 2224/84005		DELETE
H01L 2224/84007		DELETE
H01L 2224/84009		DELETE
H01L 2224/8401		DELETE
H01L 2224/84011		DELETE
H01L 2224/84012		DELETE
H01L 2224/84013		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/84014		DELETE
H01L 2224/84019		DELETE
H01L 2224/8402		DELETE
H01L 2224/8403		DELETE
H01L 2224/84031		DELETE
H01L 2224/84035		DELETE
H01L 2224/84037		DELETE
H01L 2224/84039		DELETE
H01L 2224/84041		DELETE
H01L 2224/84043		DELETE
H01L 2224/84045		DELETE
H01L 2224/84047		DELETE
H01L 2224/84048		DELETE
H01L 2224/84051		DELETE
H01L 2224/84053		DELETE
H01L 2224/84054		DELETE
H01L 2224/84055		DELETE
H01L 2224/84065		DELETE
H01L 2224/84075		DELETE
H01L 2224/84085		DELETE
H01L 2224/8409		DELETE
H01L 2224/84091		DELETE
H01L 2224/84092		DELETE
H01L 2224/84093		DELETE
H01L 2224/84095		DELETE
H01L 2224/84096		DELETE
H01L 2224/84097		DELETE
H01L 2224/84098		DELETE
H01L 2224/84099		DELETE
H01L 2224/841		DELETE
H01L 2224/8411		DELETE
H01L 2224/8412		DELETE
H01L 2224/84121		DELETE
H01L 2224/84122		DELETE
H01L 2224/84123		DELETE
H01L 2224/84125		DELETE
H01L 2224/84127		DELETE
H01L 2224/84129		DELETE
H01L 2224/8413		DELETE
H01L 2224/84132		DELETE
H01L 2224/84136		DELETE
H01L 2224/84138		DELETE
H01L 2224/84143		DELETE
H01L 2224/84148		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/84149		DELETE
H01L 2224/8415		DELETE
H01L 2224/8416		DELETE
H01L 2224/84169		DELETE
H01L 2224/8417		DELETE
H01L 2224/8418		DELETE
H01L 2224/84181		DELETE
H01L 2224/84186		DELETE
H01L 2224/84191		DELETE
H01L 2224/84196		DELETE
H01L 2224/842		DELETE
H01L 2224/84201		DELETE
H01L 2224/84203		DELETE
H01L 2224/84205		DELETE
H01L 2224/84206		DELETE
H01L 2224/84207		DELETE
H01L 2224/8421		DELETE
H01L 2224/84212		DELETE
H01L 2224/84214		DELETE
H01L 2224/8423		DELETE
H01L 2224/84232		DELETE
H01L 2224/84234		DELETE
H01L 2224/84236		DELETE
H01L 2224/84237		DELETE
H01L 2224/84238		DELETE
H01L 2224/8434		DELETE
H01L 2224/84345		DELETE
H01L 2224/84355		DELETE
H01L 2224/84359		DELETE
H01L 2224/8436		DELETE
H01L 2224/84365		DELETE
H01L 2224/84375		DELETE
H01L 2224/84379		DELETE
H01L 2224/8438		DELETE
H01L 2224/84385		DELETE
H01L 2224/84395		DELETE
H01L 2224/84399		DELETE
H01L 2224/844		DELETE
H01L 2224/84401		DELETE
H01L 2224/84405		DELETE
H01L 2224/84409		DELETE
H01L 2224/84411		DELETE
H01L 2224/84413		DELETE
H01L 2224/84414		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/84416		DELETE
H01L 2224/84417		DELETE
H01L 2224/84418		DELETE
H01L 2224/8442		DELETE
H01L 2224/84423		DELETE
H01L 2224/84424		DELETE
H01L 2224/84438		DELETE
H01L 2224/84439		DELETE
H01L 2224/84444		DELETE
H01L 2224/84447		DELETE
H01L 2224/84449		DELETE
H01L 2224/84455		DELETE
H01L 2224/84457		DELETE
H01L 2224/8446		DELETE
H01L 2224/84463		DELETE
H01L 2224/84464		DELETE
H01L 2224/84466		DELETE
H01L 2224/84469		DELETE
H01L 2224/8447		DELETE
H01L 2224/84471		DELETE
H01L 2224/84472		DELETE
H01L 2224/84473		DELETE
H01L 2224/84476		DELETE
H01L 2224/84478		DELETE
H01L 2224/84479		DELETE
H01L 2224/8448		DELETE
H01L 2224/84481		DELETE
H01L 2224/84483		DELETE
H01L 2224/84484		DELETE
H01L 2224/84486		DELETE
H01L 2224/84487		DELETE
H01L 2224/84488		DELETE
H01L 2224/8449		DELETE
H01L 2224/84491		DELETE
H01L 2224/84493		DELETE
H01L 2224/84494		DELETE
H01L 2224/84495		DELETE
H01L 2224/84498		DELETE
H01L 2224/84499		DELETE
H01L 2224/845		DELETE
H01L 2224/84501		DELETE
H01L 2224/84505		DELETE
H01L 2224/84509		DELETE
H01L 2224/84511		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/84513		DELETE
H01L 2224/84514		DELETE
H01L 2224/84516		DELETE
H01L 2224/84517		DELETE
H01L 2224/84518		DELETE
H01L 2224/8452		DELETE
H01L 2224/84523		DELETE
H01L 2224/84524		DELETE
H01L 2224/84538		DELETE
H01L 2224/84539		DELETE
H01L 2224/84544		DELETE
H01L 2224/84547		DELETE
H01L 2224/84549		DELETE
H01L 2224/84555		DELETE
H01L 2224/84557		DELETE
H01L 2224/8456		DELETE
H01L 2224/84563		DELETE
H01L 2224/84564		DELETE
H01L 2224/84566		DELETE
H01L 2224/84569		DELETE
H01L 2224/8457		DELETE
H01L 2224/84571		DELETE
H01L 2224/84572		DELETE
H01L 2224/84573		DELETE
H01L 2224/84576		DELETE
H01L 2224/84578		DELETE
H01L 2224/84579		DELETE
H01L 2224/8458		DELETE
H01L 2224/84581		DELETE
H01L 2224/84583		DELETE
H01L 2224/84584		DELETE
H01L 2224/84586		DELETE
H01L 2224/84587		DELETE
H01L 2224/84588		DELETE
H01L 2224/8459		DELETE
H01L 2224/84591		DELETE
H01L 2224/84593		DELETE
H01L 2224/84594		DELETE
H01L 2224/84595		DELETE
H01L 2224/84598		DELETE
H01L 2224/84599		DELETE
H01L 2224/846		DELETE
H01L 2224/84601		DELETE
H01L 2224/84605		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/84609		DELETE
H01L 2224/84611		DELETE
H01L 2224/84613		DELETE
H01L 2224/84614		DELETE
H01L 2224/84616		DELETE
H01L 2224/84617		DELETE
H01L 2224/84618		DELETE
H01L 2224/8462		DELETE
H01L 2224/84623		DELETE
H01L 2224/84624		DELETE
H01L 2224/84638		DELETE
H01L 2224/84639		DELETE
H01L 2224/84644		DELETE
H01L 2224/84647		DELETE
H01L 2224/84649		DELETE
H01L 2224/84655		DELETE
H01L 2224/84657		DELETE
H01L 2224/8466		DELETE
H01L 2224/84663		DELETE
H01L 2224/84664		DELETE
H01L 2224/84666		DELETE
H01L 2224/84669		DELETE
H01L 2224/8467		DELETE
H01L 2224/84671		DELETE
H01L 2224/84672		DELETE
H01L 2224/84673		DELETE
H01L 2224/84676		DELETE
H01L 2224/84678		DELETE
H01L 2224/84679		DELETE
H01L 2224/8468		DELETE
H01L 2224/84681		DELETE
H01L 2224/84683		DELETE
H01L 2224/84684		DELETE
H01L 2224/84686		DELETE
H01L 2224/84687		DELETE
H01L 2224/84688		DELETE
H01L 2224/8469		DELETE
H01L 2224/84691		DELETE
H01L 2224/84693		DELETE
H01L 2224/84694		DELETE
H01L 2224/84695		DELETE
H01L 2224/84698		DELETE
H01L 2224/84699		DELETE
H01L 2224/847		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/84701		DELETE
H01L 2224/84705		DELETE
H01L 2224/84709		DELETE
H01L 2224/84711		DELETE
H01L 2224/84713		DELETE
H01L 2224/84714		DELETE
H01L 2224/84716		DELETE
H01L 2224/84717		DELETE
H01L 2224/84718		DELETE
H01L 2224/8472		DELETE
H01L 2224/84723		DELETE
H01L 2224/84724		DELETE
H01L 2224/84738		DELETE
H01L 2224/84739		DELETE
H01L 2224/84744		DELETE
H01L 2224/84747		DELETE
H01L 2224/84749		DELETE
H01L 2224/84755		DELETE
H01L 2224/84757		DELETE
H01L 2224/8476		DELETE
H01L 2224/84763		DELETE
H01L 2224/84764		DELETE
H01L 2224/84766		DELETE
H01L 2224/84769		DELETE
H01L 2224/8477		DELETE
H01L 2224/84771		DELETE
H01L 2224/84772		DELETE
H01L 2224/84773		DELETE
H01L 2224/84776		DELETE
H01L 2224/84778		DELETE
H01L 2224/84779		DELETE
H01L 2224/8478		DELETE
H01L 2224/84781		DELETE
H01L 2224/84783		DELETE
H01L 2224/84784		DELETE
H01L 2224/84786		DELETE
H01L 2224/84787		DELETE
H01L 2224/84788		DELETE
H01L 2224/8479		DELETE
H01L 2224/84791		DELETE
H01L 2224/84793		DELETE
H01L 2224/84794		DELETE
H01L 2224/84795		DELETE
H01L 2224/84798		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/84799		DELETE
H01L 2224/848		DELETE
H01L 2224/84801		DELETE
H01L 2224/84805		DELETE
H01L 2224/8481		DELETE
H01L 2224/84815		DELETE
H01L 2224/8482		DELETE
H01L 2224/84825		DELETE
H01L 2224/8483		DELETE
H01L 2224/8484		DELETE
H01L 2224/8485		DELETE
H01L 2224/84855		DELETE
H01L 2224/84856		DELETE
H01L 2224/84859		DELETE
H01L 2224/84862		DELETE
H01L 2224/84865		DELETE
H01L 2224/84868		DELETE
H01L 2224/84871		DELETE
H01L 2224/84874		DELETE
H01L 2224/84877		DELETE
H01L 2224/8488		DELETE
H01L 2224/84885		DELETE
H01L 2224/8489		DELETE
H01L 2224/84893		DELETE
H01L 2224/84895		DELETE
H01L 2224/84897		DELETE
H01L 2224/84898		DELETE
H01L 2224/84899		DELETE
H01L 2224/849		DELETE
H01L 2224/84909		DELETE
H01L 2224/8491		DELETE
H01L 2224/84911		DELETE
H01L 2224/84912		DELETE
H01L 2224/84913		DELETE
H01L 2224/84914		DELETE
H01L 2224/84919		DELETE
H01L 2224/8492		DELETE
H01L 2224/8493		DELETE
H01L 2224/84931		DELETE
H01L 2224/84935		DELETE
H01L 2224/84937		DELETE
H01L 2224/84939		DELETE
H01L 2224/84941		DELETE
H01L 2224/84943		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/84945		DELETE
H01L 2224/84947		DELETE
H01L 2224/84948		DELETE
H01L 2224/84951		DELETE
H01L 2224/84986		DELETE
H01L 2224/85		DELETE
H01L 2224/85001		DELETE
H01L 2224/85002		DELETE
H01L 2224/85005		DELETE
H01L 2224/85007		DELETE
H01L 2224/85009		DELETE
H01L 2224/8501		DELETE
H01L 2224/85011		DELETE
H01L 2224/85012		DELETE
H01L 2224/85013		DELETE
H01L 2224/85014		DELETE
H01L 2224/85016		DELETE
H01L 2224/85017		DELETE
H01L 2224/85019		DELETE
H01L 2224/8502		DELETE
H01L 2224/8503		DELETE
H01L 2224/85031		DELETE
H01L 2224/85035		DELETE
H01L 2224/85037		DELETE
H01L 2224/85039		DELETE
H01L 2224/85041		DELETE
H01L 2224/85043		DELETE
H01L 2224/85045		DELETE
H01L 2224/85047		DELETE
H01L 2224/85048		DELETE
H01L 2224/85051		DELETE
H01L 2224/85053		DELETE
H01L 2224/85054		DELETE
H01L 2224/85055		DELETE
H01L 2224/85065		DELETE
H01L 2224/85075		DELETE
H01L 2224/85085		DELETE
H01L 2224/8509		DELETE
H01L 2224/85091		DELETE
H01L 2224/85092		DELETE
H01L 2224/85093		DELETE
H01L 2224/85095		DELETE
H01L 2224/85096		DELETE
H01L 2224/85097		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/85098		DELETE
H01L 2224/85099		DELETE
H01L 2224/851		DELETE
H01L 2224/8511		DELETE
H01L 2224/8512		DELETE
H01L 2224/85121		DELETE
H01L 2224/85122		DELETE
H01L 2224/85123		DELETE
H01L 2224/85125		DELETE
H01L 2224/85127		DELETE
H01L 2224/85129		DELETE
H01L 2224/8513		DELETE
H01L 2224/85132		DELETE
H01L 2224/85136		DELETE
H01L 2224/85138		DELETE
H01L 2224/85143		DELETE
H01L 2224/85148		DELETE
H01L 2224/85149		DELETE
H01L 2224/8515		DELETE
H01L 2224/8516		DELETE
H01L 2224/85169		DELETE
H01L 2224/8517		DELETE
H01L 2224/8518		DELETE
H01L 2224/85181		DELETE
H01L 2224/85186		DELETE
H01L 2224/85191		DELETE
H01L 2224/85196		DELETE
H01L 2224/852		DELETE
H01L 2224/85201		DELETE
H01L 2224/85203		DELETE
H01L 2224/85205		DELETE
H01L 2224/85206		DELETE
H01L 2224/85207		DELETE
H01L 2224/8521		DELETE
H01L 2224/85212		DELETE
H01L 2224/85214		DELETE
H01L 2224/8523		DELETE
H01L 2224/85232		DELETE
H01L 2224/85234		DELETE
H01L 2224/85236		DELETE
H01L 2224/85237		DELETE
H01L 2224/85238		DELETE
H01L 2224/8534		DELETE
H01L 2224/85345		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/85355		DELETE
H01L 2224/85359		DELETE
H01L 2224/8536		DELETE
H01L 2224/85365		DELETE
H01L 2224/85375		DELETE
H01L 2224/85379		DELETE
H01L 2224/8538		DELETE
H01L 2224/85385		DELETE
H01L 2224/85395		DELETE
H01L 2224/85399		DELETE
H01L 2224/854		DELETE
H01L 2224/85401		DELETE
H01L 2224/85405		DELETE
H01L 2224/85409		DELETE
H01L 2224/85411		DELETE
H01L 2224/85413		DELETE
H01L 2224/85414		DELETE
H01L 2224/85416		DELETE
H01L 2224/85417		DELETE
H01L 2224/85418		DELETE
H01L 2224/8542		DELETE
H01L 2224/85423		DELETE
H01L 2224/85424		DELETE
H01L 2224/85438		DELETE
H01L 2224/85439		DELETE
H01L 2224/85444		DELETE
H01L 2224/85447		DELETE
H01L 2224/85449		DELETE
H01L 2224/85455		DELETE
H01L 2224/85457		DELETE
H01L 2224/8546		DELETE
H01L 2224/85463		DELETE
H01L 2224/85464		DELETE
H01L 2224/85466		DELETE
H01L 2224/85469		DELETE
H01L 2224/8547		DELETE
H01L 2224/85471		DELETE
H01L 2224/85472		DELETE
H01L 2224/85473		DELETE
H01L 2224/85476		DELETE
H01L 2224/85478		DELETE
H01L 2224/85479		DELETE
H01L 2224/8548		DELETE
H01L 2224/85481		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/85483		DELETE
H01L 2224/85484		DELETE
H01L 2224/85486		DELETE
H01L 2224/85487		DELETE
H01L 2224/85488		DELETE
H01L 2224/8549		DELETE
H01L 2224/85491		DELETE
H01L 2224/85493		DELETE
H01L 2224/85494		DELETE
H01L 2224/85495		DELETE
H01L 2224/85498		DELETE
H01L 2224/85499		DELETE
H01L 2224/855		DELETE
H01L 2224/85501		DELETE
H01L 2224/85505		DELETE
H01L 2224/85509		DELETE
H01L 2224/85511		DELETE
H01L 2224/85513		DELETE
H01L 2224/85514		DELETE
H01L 2224/85516		DELETE
H01L 2224/85517		DELETE
H01L 2224/85518		DELETE
H01L 2224/8552		DELETE
H01L 2224/85523		DELETE
H01L 2224/85524		DELETE
H01L 2224/85538		DELETE
H01L 2224/85539		DELETE
H01L 2224/85544		DELETE
H01L 2224/85547		DELETE
H01L 2224/85549		DELETE
H01L 2224/85555		DELETE
H01L 2224/85557		DELETE
H01L 2224/8556		DELETE
H01L 2224/85563		DELETE
H01L 2224/85564		DELETE
H01L 2224/85566		DELETE
H01L 2224/85569		DELETE
H01L 2224/8557		DELETE
H01L 2224/85571		DELETE
H01L 2224/85572		DELETE
H01L 2224/85573		DELETE
H01L 2224/85576		DELETE
H01L 2224/85578		DELETE
H01L 2224/85579		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/8558		DELETE
H01L 2224/85581		DELETE
H01L 2224/85583		DELETE
H01L 2224/85584		DELETE
H01L 2224/85586		DELETE
H01L 2224/85587		DELETE
H01L 2224/85588		DELETE
H01L 2224/8559		DELETE
H01L 2224/85591		DELETE
H01L 2224/85593		DELETE
H01L 2224/85594		DELETE
H01L 2224/85595		DELETE
H01L 2224/85598		DELETE
H01L 2224/85599		DELETE
H01L 2224/856		DELETE
H01L 2224/85601		DELETE
H01L 2224/85605		DELETE
H01L 2224/85609		DELETE
H01L 2224/85611		DELETE
H01L 2224/85613		DELETE
H01L 2224/85614		DELETE
H01L 2224/85616		DELETE
H01L 2224/85617		DELETE
H01L 2224/85618		DELETE
H01L 2224/8562		DELETE
H01L 2224/85623		DELETE
H01L 2224/85624		DELETE
H01L 2224/85638		DELETE
H01L 2224/85639		DELETE
H01L 2224/85644		DELETE
H01L 2224/85647		DELETE
H01L 2224/85649		DELETE
H01L 2224/85655		DELETE
H01L 2224/85657		DELETE
H01L 2224/8566		DELETE
H01L 2224/85663		DELETE
H01L 2224/85664		DELETE
H01L 2224/85666		DELETE
H01L 2224/85669		DELETE
H01L 2224/8567		DELETE
H01L 2224/85671		DELETE
H01L 2224/85672		DELETE
H01L 2224/85673		DELETE
H01L 2224/85676		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/85678		DELETE
H01L 2224/85679		DELETE
H01L 2224/8568		DELETE
H01L 2224/85681		DELETE
H01L 2224/85683		DELETE
H01L 2224/85684		DELETE
H01L 2224/85686		DELETE
H01L 2224/85687		DELETE
H01L 2224/85688		DELETE
H01L 2224/8569		DELETE
H01L 2224/85691		DELETE
H01L 2224/85693		DELETE
H01L 2224/85694		DELETE
H01L 2224/85695		DELETE
H01L 2224/85698		DELETE
H01L 2224/85699		DELETE
H01L 2224/857		DELETE
H01L 2224/85701		DELETE
H01L 2224/85705		DELETE
H01L 2224/85709		DELETE
H01L 2224/85711		DELETE
H01L 2224/85713		DELETE
H01L 2224/85714		DELETE
H01L 2224/85716		DELETE
H01L 2224/85717		DELETE
H01L 2224/85718		DELETE
H01L 2224/8572		DELETE
H01L 2224/85723		DELETE
H01L 2224/85724		DELETE
H01L 2224/85738		DELETE
H01L 2224/85739		DELETE
H01L 2224/85744		DELETE
H01L 2224/85747		DELETE
H01L 2224/85749		DELETE
H01L 2224/85755		DELETE
H01L 2224/85757		DELETE
H01L 2224/8576		DELETE
H01L 2224/85763		DELETE
H01L 2224/85764		DELETE
H01L 2224/85766		DELETE
H01L 2224/85769		DELETE
H01L 2224/8577		DELETE
H01L 2224/85771		DELETE
H01L 2224/85772		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/85773		DELETE
H01L 2224/85776		DELETE
H01L 2224/85778		DELETE
H01L 2224/85779		DELETE
H01L 2224/8578		DELETE
H01L 2224/85781		DELETE
H01L 2224/85783		DELETE
H01L 2224/85784		DELETE
H01L 2224/85786		DELETE
H01L 2224/85787		DELETE
H01L 2224/85788		DELETE
H01L 2224/8579		DELETE
H01L 2224/85791		DELETE
H01L 2224/85793		DELETE
H01L 2224/85794		DELETE
H01L 2224/85795		DELETE
H01L 2224/85798		DELETE
H01L 2224/85799		DELETE
H01L 2224/858		DELETE
H01L 2224/85801		DELETE
H01L 2224/85805		DELETE
H01L 2224/8581		DELETE
H01L 2224/85815		DELETE
H01L 2224/8582		DELETE
H01L 2224/85825		DELETE
H01L 2224/8583		DELETE
H01L 2224/8584		DELETE
H01L 2224/8585		DELETE
H01L 2224/85855		DELETE
H01L 2224/85856		DELETE
H01L 2224/85859		DELETE
H01L 2224/85862		DELETE
H01L 2224/85865		DELETE
H01L 2224/85868		DELETE
H01L 2224/85871		DELETE
H01L 2224/85874		DELETE
H01L 2224/85877		DELETE
H01L 2224/8588		DELETE
H01L 2224/85885		DELETE
H01L 2224/8589		DELETE
H01L 2224/85893		DELETE
H01L 2224/85895		DELETE
H01L 2224/85897		DELETE
H01L 2224/85898		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/85899		DELETE
H01L 2224/859		DELETE
H01L 2224/85909		DELETE
H01L 2224/8591		DELETE
H01L 2224/85911		DELETE
H01L 2224/85912		DELETE
H01L 2224/85913		DELETE
H01L 2224/85914		DELETE
H01L 2224/85916		DELETE
H01L 2224/85917		DELETE
H01L 2224/85919		DELETE
H01L 2224/8592		DELETE
H01L 2224/8593		DELETE
H01L 2224/85931		DELETE
H01L 2224/85935		DELETE
H01L 2224/85937		DELETE
H01L 2224/85939		DELETE
H01L 2224/85941		DELETE
H01L 2224/85943		DELETE
H01L 2224/85945		DELETE
H01L 2224/85947		DELETE
H01L 2224/85948		DELETE
H01L 2224/85951		DELETE
H01L 2224/85986		DELETE
H01L 2224/86		DELETE
H01L 2224/86001		DELETE
H01L 2224/86002		DELETE
H01L 2224/86005		DELETE
H01L 2224/86007		DELETE
H01L 2224/86009		DELETE
H01L 2224/8601		DELETE
H01L 2224/8603		DELETE
H01L 2224/86031		DELETE
H01L 2224/86035		DELETE
H01L 2224/86039		DELETE
H01L 2224/86045		DELETE
H01L 2224/86047		DELETE
H01L 2224/86048		DELETE
H01L 2224/86051		DELETE
H01L 2224/86053		DELETE
H01L 2224/86054		DELETE
H01L 2224/86085		DELETE
H01L 2224/8609		DELETE
H01L 2224/86091		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/86095		DELETE
H01L 2224/86096		DELETE
H01L 2224/86097		DELETE
H01L 2224/86098		DELETE
H01L 2224/86099		DELETE
H01L 2224/861		DELETE
H01L 2224/8611		DELETE
H01L 2224/8612		DELETE
H01L 2224/86121		DELETE
H01L 2224/86122		DELETE
H01L 2224/8613		DELETE
H01L 2224/86132		DELETE
H01L 2224/86136		DELETE
H01L 2224/86138		DELETE
H01L 2224/86143		DELETE
H01L 2224/86148		DELETE
H01L 2224/86149		DELETE
H01L 2224/8615		DELETE
H01L 2224/8616		DELETE
H01L 2224/86169		DELETE
H01L 2224/8617		DELETE
H01L 2224/8618		DELETE
H01L 2224/86181		DELETE
H01L 2224/86186		DELETE
H01L 2224/86191		DELETE
H01L 2224/862		DELETE
H01L 2224/86201		DELETE
H01L 2224/86203		DELETE
H01L 2224/86205		DELETE
H01L 2224/86207		DELETE
H01L 2224/8621		DELETE
H01L 2224/86212		DELETE
H01L 2224/86214		DELETE
H01L 2224/8623		DELETE
H01L 2224/86232		DELETE
H01L 2224/86234		DELETE
H01L 2224/86236		DELETE
H01L 2224/86237		DELETE
H01L 2224/86238		DELETE
H01L 2224/8634		DELETE
H01L 2224/86345		DELETE
H01L 2224/86355		DELETE
H01L 2224/86359		DELETE
H01L 2224/8636		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/86365		DELETE
H01L 2224/86375		DELETE
H01L 2224/86379		DELETE
H01L 2224/8638		DELETE
H01L 2224/86385		DELETE
H01L 2224/86395		DELETE
H01L 2224/86399		DELETE
H01L 2224/868		DELETE
H01L 2224/86801		DELETE
H01L 2224/86805		DELETE
H01L 2224/8681		DELETE
H01L 2224/86815		DELETE
H01L 2224/8682		DELETE
H01L 2224/86825		DELETE
H01L 2224/8683		DELETE
H01L 2224/8684		DELETE
H01L 2224/8685		DELETE
H01L 2224/86855		DELETE
H01L 2224/86856		DELETE
H01L 2224/86859		DELETE
H01L 2224/86862		DELETE
H01L 2224/86865		DELETE
H01L 2224/86868		DELETE
H01L 2224/86871		DELETE
H01L 2224/86874		DELETE
H01L 2224/86877		DELETE
H01L 2224/8688		DELETE
H01L 2224/86885		DELETE
H01L 2224/8689		DELETE
H01L 2224/86893		DELETE
H01L 2224/86895		DELETE
H01L 2224/86896		DELETE
H01L 2224/86897		DELETE
H01L 2224/86899		DELETE
H01L 2224/869		DELETE
H01L 2224/86909		DELETE
H01L 2224/8691		DELETE
H01L 2224/8693		DELETE
H01L 2224/86931		DELETE
H01L 2224/86935		DELETE
H01L 2224/86939		DELETE
H01L 2224/86945		DELETE
H01L 2224/86947		DELETE
H01L 2224/86948		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/86951		DELETE
H01L 2224/86986		DELETE
H01L 2224/89		DELETE
H01L 2224/90		DELETE
H01L 2224/91		DELETE
H01L 2224/92		DELETE
H01L 2224/9201		DELETE
H01L 2224/9202		DELETE
H01L 2224/9205		DELETE
H01L 2224/921		DELETE
H01L 2224/9211		DELETE
H01L 2224/9212		DELETE
H01L 2224/92122		DELETE
H01L 2224/92124		DELETE
H01L 2224/92125		DELETE
H01L 2224/92127		DELETE
H01L 2224/92132		DELETE
H01L 2224/92133		DELETE
H01L 2224/92135		DELETE
H01L 2224/92136		DELETE
H01L 2224/92137		DELETE
H01L 2224/92138		DELETE
H01L 2224/92142		DELETE
H01L 2224/92143		DELETE
H01L 2224/92144		DELETE
H01L 2224/92147		DELETE
H01L 2224/92148		DELETE
H01L 2224/92152		DELETE
H01L 2224/92153		DELETE
H01L 2224/92155		DELETE
H01L 2224/92157		DELETE
H01L 2224/92158		DELETE
H01L 2224/92162		DELETE
H01L 2224/92163		DELETE
H01L 2224/92164		DELETE
H01L 2224/92165		DELETE
H01L 2224/92166		DELETE
H01L 2224/92168		DELETE
H01L 2224/92172		DELETE
H01L 2224/92173		DELETE
H01L 2224/92174		DELETE
H01L 2224/92175		DELETE
H01L 2224/92176		DELETE
H01L 2224/92177		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/922		DELETE
H01L 2224/9221		DELETE
H01L 2224/9222		DELETE
H01L 2224/92222		DELETE
H01L 2224/92224		DELETE
H01L 2224/92225		DELETE
H01L 2224/92226		DELETE
H01L 2224/92227		DELETE
H01L 2224/92228		DELETE
H01L 2224/92242		DELETE
H01L 2224/92244		DELETE
H01L 2224/92246		DELETE
H01L 2224/92247		DELETE
H01L 2224/92248		DELETE
H01L 2224/92252		DELETE
H01L 2224/92253		DELETE
H01L 2224/92255		DELETE
H01L 2224/93		DELETE
H01L 2224/94		DELETE
H01L 2224/95		DELETE
H01L 2224/95001		DELETE
H01L 2224/95053		DELETE
H01L 2224/95085		DELETE
H01L 2224/95091		DELETE
H01L 2224/95092		DELETE
H01L 2224/95093		DELETE
H01L 2224/951		DELETE
H01L 2224/95101		DELETE
H01L 2224/95102		DELETE
H01L 2224/9511		DELETE
H01L 2224/95115		DELETE
H01L 2224/9512		DELETE
H01L 2224/95121		DELETE
H01L 2224/95122		DELETE
H01L 2224/95123		DELETE
H01L 2224/95133		DELETE
H01L 2224/95134		DELETE
H01L 2224/95136		DELETE
H01L 2224/95143		DELETE
H01L 2224/95144		DELETE
H01L 2224/95145		DELETE
H01L 2224/95146		DELETE
H01L 2224/95147		DELETE
H01L 2224/95148		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2224/96		DELETE
H01L 2224/97		DELETE
H01L 2224/98		DELETE
H01L 2225/00		DELETE
H01L 2225/03		DELETE
H01L 2225/04		DELETE
H01L 2225/065		DELETE
H01L 2225/06503		DELETE
H01L 2225/06506		DELETE
H01L 2225/0651		DELETE
H01L 2225/06513		DELETE
H01L 2225/06517		DELETE
H01L 2225/0652		DELETE
H01L 2225/06524		DELETE
H01L 2225/06527		DELETE
H01L 2225/06531		DELETE
H01L 2225/06534		DELETE
H01L 2225/06537		DELETE
H01L 2225/06541		DELETE
H01L 2225/06544		DELETE
H01L 2225/06548		DELETE
H01L 2225/06551		DELETE
H01L 2225/06555		DELETE
H01L 2225/06558		DELETE
H01L 2225/06562		DELETE
H01L 2225/06565		DELETE
H01L 2225/06568		DELETE
H01L 2225/06572		DELETE
H01L 2225/06575		DELETE
H01L 2225/06579		DELETE
H01L 2225/06582		DELETE
H01L 2225/06586		DELETE
H01L 2225/06589		DELETE
H01L 2225/06593		DELETE
H01L 2225/06596		DELETE
H01L 2225/10		DELETE
H01L 2225/1005		DELETE
H01L 2225/1011		DELETE
H01L 2225/1017		DELETE
H01L 2225/1023		DELETE
H01L 2225/1029		DELETE
H01L 2225/1035		DELETE
H01L 2225/1041		DELETE
H01L 2225/1047		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2225/1052		DELETE
H01L 2225/1058		DELETE
H01L 2225/1064		DELETE
H01L 2225/107		DELETE
H01L 2225/1076		DELETE
H01L 2225/1082		DELETE
H01L 2225/1088		DELETE
H01L 2225/1094		DELETE
H01L 2924/00		DELETE
H01L 2924/0001		DELETE
H01L 2924/00011		DELETE
H01L 2924/00012		DELETE
H01L 2924/00013		DELETE
H01L 2924/00014		DELETE
H01L 2924/00015		DELETE
H01L 2924/0002		DELETE
H01L 2924/01		DELETE
H01L 2924/01001		DELETE
H01L 2924/01002		DELETE
H01L 2924/01003		DELETE
H01L 2924/01004		DELETE
H01L 2924/01005		DELETE
H01L 2924/01006		DELETE
H01L 2924/01007		DELETE
H01L 2924/01008		DELETE
H01L 2924/01009		DELETE
H01L 2924/0101		DELETE
H01L 2924/01011		DELETE
H01L 2924/01012		DELETE
H01L 2924/01013		DELETE
H01L 2924/01014		DELETE
H01L 2924/01015		DELETE
H01L 2924/01016		DELETE
H01L 2924/01017		DELETE
H01L 2924/01018		DELETE
H01L 2924/01019		DELETE
H01L 2924/0102		DELETE
H01L 2924/01021		DELETE
H01L 2924/01022		DELETE
H01L 2924/01023		DELETE
H01L 2924/01024		DELETE
H01L 2924/01025		DELETE
H01L 2924/01026		DELETE
H01L 2924/01027		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2924/01028		DELETE
H01L 2924/01029		DELETE
H01L 2924/0103		DELETE
H01L 2924/01031		DELETE
H01L 2924/01032		DELETE
H01L 2924/01033		DELETE
H01L 2924/01034		DELETE
H01L 2924/01035		DELETE
H01L 2924/01036		DELETE
H01L 2924/01037		DELETE
H01L 2924/01038		DELETE
H01L 2924/01039		DELETE
H01L 2924/0104		DELETE
H01L 2924/01041		DELETE
H01L 2924/01042		DELETE
H01L 2924/01043		DELETE
H01L 2924/01044		DELETE
H01L 2924/01045		DELETE
H01L 2924/01046		DELETE
H01L 2924/01047		DELETE
H01L 2924/01048		DELETE
H01L 2924/01049		DELETE
H01L 2924/0105		DELETE
H01L 2924/01051		DELETE
H01L 2924/01052		DELETE
H01L 2924/01053		DELETE
H01L 2924/01054		DELETE
H01L 2924/01055		DELETE
H01L 2924/01056		DELETE
H01L 2924/01057		DELETE
H01L 2924/01058		DELETE
H01L 2924/01059		DELETE
H01L 2924/0106		DELETE
H01L 2924/01061		DELETE
H01L 2924/01062		DELETE
H01L 2924/01063		DELETE
H01L 2924/01064		DELETE
H01L 2924/01065		DELETE
H01L 2924/01066		DELETE
H01L 2924/01067		DELETE
H01L 2924/01068		DELETE
H01L 2924/01069		DELETE
H01L 2924/0107		DELETE
H01L 2924/01071		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2924/01072		DELETE
H01L 2924/01073		DELETE
H01L 2924/01074		DELETE
H01L 2924/01075		DELETE
H01L 2924/01076		DELETE
H01L 2924/01077		DELETE
H01L 2924/01078		DELETE
H01L 2924/01079		DELETE
H01L 2924/0108		DELETE
H01L 2924/01081		DELETE
H01L 2924/01082		DELETE
H01L 2924/01083		DELETE
H01L 2924/01084		DELETE
H01L 2924/01085		DELETE
H01L 2924/01086		DELETE
H01L 2924/01087		DELETE
H01L 2924/01088		DELETE
H01L 2924/01089		DELETE
H01L 2924/0109		DELETE
H01L 2924/01091		DELETE
H01L 2924/01092		DELETE
H01L 2924/01093		DELETE
H01L 2924/01094		DELETE
H01L 2924/011		DELETE
H01L 2924/01101		DELETE
H01L 2924/01102		DELETE
H01L 2924/01103		DELETE
H01L 2924/01104		DELETE
H01L 2924/01105		DELETE
H01L 2924/01106		DELETE
H01L 2924/01107		DELETE
H01L 2924/01108		DELETE
H01L 2924/01109		DELETE
H01L 2924/0111		DELETE
H01L 2924/01111		DELETE
H01L 2924/01112		DELETE
H01L 2924/012		DELETE
H01L 2924/01201		DELETE
H01L 2924/01202		DELETE
H01L 2924/01203		DELETE
H01L 2924/01204		DELETE
H01L 2924/01205		DELETE
H01L 2924/01206		DELETE
H01L 2924/01207		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2924/01208		DELETE
H01L 2924/013		DELETE
H01L 2924/0132		DELETE
H01L 2924/01321		DELETE
H01L 2924/01322		DELETE
H01L 2924/01323		DELETE
H01L 2924/01324		DELETE
H01L 2924/01325		DELETE
H01L 2924/01326		DELETE
H01L 2924/01327		DELETE
H01L 2924/0133		DELETE
H01L 2924/0134		DELETE
H01L 2924/0135		DELETE
H01L 2924/014		DELETE
H01L 2924/01402		DELETE
H01L 2924/01403		DELETE
H01L 2924/01404		DELETE
H01L 2924/01405		DELETE
H01L 2924/042		DELETE
H01L 2924/0421		DELETE
H01L 2924/0422		DELETE
H01L 2924/0423		DELETE
H01L 2924/0424		DELETE
H01L 2924/0425		DELETE
H01L 2924/0426		DELETE
H01L 2924/0427		DELETE
H01L 2924/0428		DELETE
H01L 2924/0429		DELETE
H01L 2924/044		DELETE
H01L 2924/0441		DELETE
H01L 2924/0442		DELETE
H01L 2924/0443		DELETE
H01L 2924/0444		DELETE
H01L 2924/0445		DELETE
H01L 2924/0446		DELETE
H01L 2924/0449		DELETE
H01L 2924/04491		DELETE
H01L 2924/04492		DELETE
H01L 2924/04494		DELETE
H01L 2924/045		DELETE
H01L 2924/0451		DELETE
H01L 2924/0452		DELETE
H01L 2924/0453		DELETE
H01L 2924/0454		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2924/04541		DELETE
H01L 2924/0455		DELETE
H01L 2924/0456		DELETE
H01L 2924/04563		DELETE
H01L 2924/0457		DELETE
H01L 2924/0458		DELETE
H01L 2924/0459		DELETE
H01L 2924/046		DELETE
H01L 2924/0461		DELETE
H01L 2924/0462		DELETE
H01L 2924/0463		DELETE
H01L 2924/0464		DELETE
H01L 2924/04642		DELETE
H01L 2924/0465		DELETE
H01L 2924/0466		DELETE
H01L 2924/0469		DELETE
H01L 2924/04691		DELETE
H01L 2924/04692		DELETE
H01L 2924/04694		DELETE
H01L 2924/047		DELETE
H01L 2924/0471		DELETE
H01L 2924/0472		DELETE
H01L 2924/0473		DELETE
H01L 2924/0474		DELETE
H01L 2924/0475		DELETE
H01L 2924/0476		DELETE
H01L 2924/0477		DELETE
H01L 2924/0478		DELETE
H01L 2924/0479		DELETE
H01L 2924/048		DELETE
H01L 2924/0481		DELETE
H01L 2924/0482		DELETE
H01L 2924/0483		DELETE
H01L 2924/0484		DELETE
H01L 2924/0485		DELETE
H01L 2924/0486		DELETE
H01L 2924/0489		DELETE
H01L 2924/04891		DELETE
H01L 2924/04892		DELETE
H01L 2924/04894		DELETE
H01L 2924/049		DELETE
H01L 2924/0491		DELETE
H01L 2924/0492		DELETE
H01L 2924/0493		DELETE

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H01L 2924/0494		DELETE
H01L 2924/04941		DELETE
H01L 2924/0495		DELETE
H01L 2924/04953		DELETE
H01L 2924/0496		DELETE
H01L 2924/0497		DELETE
H01L 2924/0498		DELETE
H01L 2924/0499		DELETE
H01L 2924/05		DELETE
H01L 2924/0501		DELETE
H01L 2924/0502		DELETE
H01L 2924/0503		DELETE
H01L 2924/05032		DELETE
H01L 2924/0504		DELETE
H01L 2924/05042		DELETE
H01L 2924/0505		DELETE
H01L 2924/0506		DELETE
H01L 2924/0509		DELETE
H01L 2924/05091		DELETE
H01L 2924/05092		DELETE
H01L 2924/05094		DELETE
H01L 2924/051		DELETE
H01L 2924/0511		DELETE
H01L 2924/0512		DELETE
H01L 2924/0513		DELETE
H01L 2924/0514		DELETE
H01L 2924/0515		DELETE
H01L 2924/0516		DELETE
H01L 2924/0517		DELETE
H01L 2924/0518		DELETE
H01L 2924/0519		DELETE
H01L 2924/052		DELETE
H01L 2924/0521		DELETE
H01L 2924/0522		DELETE
H01L 2924/0523		DELETE
H01L 2924/0524		DELETE
H01L 2924/0525		DELETE
H01L 2924/0526		DELETE
H01L 2924/0529		DELETE
H01L 2924/05291		DELETE
H01L 2924/05292		DELETE
H01L 2924/05294		DELETE
H01L 2924/053		DELETE
H01L 2924/0531		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2924/0532		DELETE
H01L 2924/0533		DELETE
H01L 2924/0534		DELETE
H01L 2924/05341		DELETE
H01L 2924/05342		DELETE
H01L 2924/0535		DELETE
H01L 2924/0536		DELETE
H01L 2924/0537		DELETE
H01L 2924/0538		DELETE
H01L 2924/05381		DELETE
H01L 2924/0539		DELETE
H01L 2924/054		DELETE
H01L 2924/0541		DELETE
H01L 2924/0542		DELETE
H01L 2924/0543		DELETE
H01L 2924/05432		DELETE
H01L 2924/0544		DELETE
H01L 2924/05442		DELETE
H01L 2924/0545		DELETE
H01L 2924/0546		DELETE
H01L 2924/0549		DELETE
H01L 2924/05491		DELETE
H01L 2924/05492		DELETE
H01L 2924/05494		DELETE
H01L 2924/055		DELETE
H01L 2924/0551		DELETE
H01L 2924/0552		DELETE
H01L 2924/0553		DELETE
H01L 2924/0554		DELETE
H01L 2924/0555		DELETE
H01L 2924/0556		DELETE
H01L 2924/0557		DELETE
H01L 2924/0558		DELETE
H01L 2924/0559		DELETE
H01L 2924/056		DELETE
H01L 2924/0561		DELETE
H01L 2924/0562		DELETE
H01L 2924/0563		DELETE
H01L 2924/0564		DELETE
H01L 2924/0565		DELETE
H01L 2924/0566		DELETE
H01L 2924/0569		DELETE
H01L 2924/05691		DELETE
H01L 2924/05692		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2924/05694		DELETE
H01L 2924/057		DELETE
H01L 2924/0571		DELETE
H01L 2924/0572		DELETE
H01L 2924/0573		DELETE
H01L 2924/0574		DELETE
H01L 2924/0575		DELETE
H01L 2924/0576		DELETE
H01L 2924/0577		DELETE
H01L 2924/0578		DELETE
H01L 2924/0579		DELETE
H01L 2924/058		DELETE
H01L 2924/0581		DELETE
H01L 2924/0582		DELETE
H01L 2924/0583		DELETE
H01L 2924/0584		DELETE
H01L 2924/0585		DELETE
H01L 2924/0586		DELETE
H01L 2924/0589		DELETE
H01L 2924/05891		DELETE
H01L 2924/05892		DELETE
H01L 2924/05894		DELETE
H01L 2924/059		DELETE
H01L 2924/05991		DELETE
H01L 2924/05992		DELETE
H01L 2924/05994		DELETE
H01L 2924/06		DELETE
H01L 2924/061		DELETE
H01L 2924/0615		DELETE
H01L 2924/062		DELETE
H01L 2924/0625		DELETE
H01L 2924/063		DELETE
H01L 2924/0635		DELETE
H01L 2924/064		DELETE
H01L 2924/0645		DELETE
H01L 2924/065		DELETE
H01L 2924/0655		DELETE
H01L 2924/066		DELETE
H01L 2924/0665		DELETE
H01L 2924/067		DELETE
H01L 2924/0675		DELETE
H01L 2924/068		DELETE
H01L 2924/0685		DELETE
H01L 2924/069		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2924/0695		DELETE
H01L 2924/07		DELETE
H01L 2924/07001		DELETE
H01L 2924/07025		DELETE
H01L 2924/0705		DELETE
H01L 2924/0715		DELETE
H01L 2924/078		DELETE
H01L 2924/07802		DELETE
H01L 2924/0781		DELETE
H01L 2924/07811		DELETE
H01L 2924/07812		DELETE
H01L 2924/0782		DELETE
H01L 2924/095		DELETE
H01L 2924/0951		DELETE
H01L 2924/09511		DELETE
H01L 2924/09512		DELETE
H01L 2924/09522		DELETE
H01L 2924/09523		DELETE
H01L 2924/096		DELETE
H01L 2924/097		DELETE
H01L 2924/09701		DELETE
H01L 2924/10		DELETE
H01L 2924/1011		DELETE
H01L 2924/1015		DELETE
H01L 2924/10155		DELETE
H01L 2924/10156		DELETE
H01L 2924/10157		DELETE
H01L 2924/10158		DELETE
H01L 2924/1016		DELETE
H01L 2924/10161		DELETE
H01L 2924/10162		DELETE
H01L 2924/1017		DELETE
H01L 2924/102		DELETE
H01L 2924/1025		DELETE
H01L 2924/10251		DELETE
H01L 2924/10252		DELETE
H01L 2924/10253		DELETE
H01L 2924/10254		DELETE
H01L 2924/1026		DELETE
H01L 2924/1027		DELETE
H01L 2924/10271		DELETE
H01L 2924/10272		DELETE
H01L 2924/1032		DELETE
H01L 2924/10321		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2924/10322		DELETE
H01L 2924/10323		DELETE
H01L 2924/10324		DELETE
H01L 2924/10325		DELETE
H01L 2924/10326		DELETE
H01L 2924/10327		DELETE
H01L 2924/10328		DELETE
H01L 2924/10329		DELETE
H01L 2924/1033		DELETE
H01L 2924/10331		DELETE
H01L 2924/10332		DELETE
H01L 2924/10333		DELETE
H01L 2924/10334		DELETE
H01L 2924/10335		DELETE
H01L 2924/10336		DELETE
H01L 2924/10337		DELETE
H01L 2924/10338		DELETE
H01L 2924/10339		DELETE
H01L 2924/1034		DELETE
H01L 2924/10341		DELETE
H01L 2924/10342		DELETE
H01L 2924/10343		DELETE
H01L 2924/10344		DELETE
H01L 2924/10345		DELETE
H01L 2924/10346		DELETE
H01L 2924/10347		DELETE
H01L 2924/10348		DELETE
H01L 2924/10349		DELETE
H01L 2924/1035		DELETE
H01L 2924/10351		DELETE
H01L 2924/10352		DELETE
H01L 2924/10353		DELETE
H01L 2924/10354		DELETE
H01L 2924/10355		DELETE
H01L 2924/10356		DELETE
H01L 2924/10357		DELETE
H01L 2924/10358		DELETE
H01L 2924/10359		DELETE
H01L 2924/1036		DELETE
H01L 2924/1037		DELETE
H01L 2924/10371		DELETE
H01L 2924/10372		DELETE
H01L 2924/10373		DELETE
H01L 2924/10375		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2924/10376		DELETE
H01L 2924/10377		DELETE
H01L 2924/10378		DELETE
H01L 2924/10379		DELETE
H01L 2924/1038		DELETE
H01L 2924/10381		DELETE
H01L 2924/1042		DELETE
H01L 2924/10421		DELETE
H01L 2924/1047		DELETE
H01L 2924/10471		DELETE
H01L 2924/1052		DELETE
H01L 2924/10521		DELETE
H01L 2924/10522		DELETE
H01L 2924/10523		DELETE
H01L 2924/10524		DELETE
H01L 2924/10525		DELETE
H01L 2924/10526		DELETE
H01L 2924/10527		DELETE
H01L 2924/10528		DELETE
H01L 2924/1057		DELETE
H01L 2924/10571		DELETE
H01L 2924/1062		DELETE
H01L 2924/10621		DELETE
H01L 2924/10622		DELETE
H01L 2924/10623		DELETE
H01L 2924/10624		DELETE
H01L 2924/10625		DELETE
H01L 2924/10626		DELETE
H01L 2924/1067		DELETE
H01L 2924/10671		DELETE
H01L 2924/10672		DELETE
H01L 2924/10673		DELETE
H01L 2924/10674		DELETE
H01L 2924/10675		DELETE
H01L 2924/10676		DELETE
H01L 2924/10677		DELETE
H01L 2924/10678		DELETE
H01L 2924/10679		DELETE
H01L 2924/1068		DELETE
H01L 2924/10681		DELETE
H01L 2924/1072		DELETE
H01L 2924/10721		DELETE
H01L 2924/10722		DELETE
H01L 2924/10723		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2924/10724		DELETE
H01L 2924/10725		DELETE
H01L 2924/1077		DELETE
H01L 2924/10771		DELETE
H01L 2924/10772		DELETE
H01L 2924/10773		DELETE
H01L 2924/10774		DELETE
H01L 2924/10775		DELETE
H01L 2924/10776		DELETE
H01L 2924/10777		DELETE
H01L 2924/10778		DELETE
H01L 2924/10779		DELETE
H01L 2924/1078		DELETE
H01L 2924/1082		DELETE
H01L 2924/10821		DELETE
H01L 2924/10822		DELETE
H01L 2924/10823		DELETE
H01L 2924/10824		DELETE
H01L 2924/10825		DELETE
H01L 2924/10826		DELETE
H01L 2924/10827		DELETE
H01L 2924/10828		DELETE
H01L 2924/10829		DELETE
H01L 2924/1083		DELETE
H01L 2924/10831		DELETE
H01L 2924/10832		DELETE
H01L 2924/10833		DELETE
H01L 2924/11		DELETE
H01L 2924/12		DELETE
H01L 2924/1203		DELETE
H01L 2924/12031		DELETE
H01L 2924/12032		DELETE
H01L 2924/12033		DELETE
H01L 2924/12034		DELETE
H01L 2924/12035		DELETE
H01L 2924/12036		DELETE
H01L 2924/12037		DELETE
H01L 2924/12038		DELETE
H01L 2924/1204		DELETE
H01L 2924/12041		DELETE
H01L 2924/12042		DELETE
H01L 2924/12043		DELETE
H01L 2924/12044		DELETE
H01L 2924/1205		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2924/1206		DELETE
H01L 2924/1207		DELETE
H01L 2924/13		DELETE
H01L 2924/1301		DELETE
H01L 2924/13011		DELETE
H01L 2924/13013		DELETE
H01L 2924/13014		DELETE
H01L 2924/13015		DELETE
H01L 2924/13016		DELETE
H01L 2924/13017		DELETE
H01L 2924/13018		DELETE
H01L 2924/13019		DELETE
H01L 2924/1302		DELETE
H01L 2924/13021		DELETE
H01L 2924/13022		DELETE
H01L 2924/13023		DELETE
H01L 2924/13024		DELETE
H01L 2924/13025		DELETE
H01L 2924/13026		DELETE
H01L 2924/13027		DELETE
H01L 2924/13028		DELETE
H01L 2924/13029		DELETE
H01L 2924/1303		DELETE
H01L 2924/13032		DELETE
H01L 2924/13033		DELETE
H01L 2924/13034		DELETE
H01L 2924/13035		DELETE
H01L 2924/1304		DELETE
H01L 2924/1305		DELETE
H01L 2924/13051		DELETE
H01L 2924/13052		DELETE
H01L 2924/13053		DELETE
H01L 2924/13054		DELETE
H01L 2924/13055		DELETE
H01L 2924/13056		DELETE
H01L 2924/1306		DELETE
H01L 2924/13061		DELETE
H01L 2924/13062		DELETE
H01L 2924/13063		DELETE
H01L 2924/13064		DELETE
H01L 2924/13066		DELETE
H01L 2924/13067		DELETE
H01L 2924/13068		DELETE
H01L 2924/13069		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2924/1307		DELETE
H01L 2924/13071		DELETE
H01L 2924/13072		DELETE
H01L 2924/13073		DELETE
H01L 2924/13074		DELETE
H01L 2924/13075		DELETE
H01L 2924/13076		DELETE
H01L 2924/13078		DELETE
H01L 2924/13079		DELETE
H01L 2924/1308		DELETE
H01L 2924/13081		DELETE
H01L 2924/13082		DELETE
H01L 2924/13083		DELETE
H01L 2924/13084		DELETE
H01L 2924/13085		DELETE
H01L 2924/13086		DELETE
H01L 2924/13087		DELETE
H01L 2924/13088		DELETE
H01L 2924/13089		DELETE
H01L 2924/1309		DELETE
H01L 2924/13091		DELETE
H01L 2924/13092		DELETE
H01L 2924/14		DELETE
H01L 2924/141		DELETE
H01L 2924/142		DELETE
H01L 2924/1421		DELETE
H01L 2924/14211		DELETE
H01L 2924/14215		DELETE
H01L 2924/1422		DELETE
H01L 2924/14221		DELETE
H01L 2924/14222		DELETE
H01L 2924/1423		DELETE
H01L 2924/1424		DELETE
H01L 2924/1425		DELETE
H01L 2924/14251		DELETE
H01L 2924/14252		DELETE
H01L 2924/14253		DELETE
H01L 2924/1426		DELETE
H01L 2924/1427		DELETE
H01L 2924/143		DELETE
H01L 2924/1431		DELETE
H01L 2924/1432		DELETE
H01L 2924/1433		DELETE
H01L 2924/14335		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2924/1434		DELETE
H01L 2924/1435		DELETE
H01L 2924/1436		DELETE
H01L 2924/14361		DELETE
H01L 2924/14362		DELETE
H01L 2924/14363		DELETE
H01L 2924/14364		DELETE
H01L 2924/14365		DELETE
H01L 2924/14366		DELETE
H01L 2924/14367		DELETE
H01L 2924/14368		DELETE
H01L 2924/14369		DELETE
H01L 2924/1437		DELETE
H01L 2924/1438		DELETE
H01L 2924/1441		DELETE
H01L 2924/1442		DELETE
H01L 2924/1443		DELETE
H01L 2924/1444		DELETE
H01L 2924/145		DELETE
H01L 2924/1451		DELETE
H01L 2924/14511		DELETE
H01L 2924/1453		DELETE
H01L 2924/146		DELETE
H01L 2924/1461		DELETE
H01L 2924/15		DELETE
H01L 2924/151		DELETE
H01L 2924/1511		DELETE
H01L 2924/1515		DELETE
H01L 2924/15151		DELETE
H01L 2924/15153		DELETE
H01L 2924/15155		DELETE
H01L 2924/15156		DELETE
H01L 2924/15157		DELETE
H01L 2924/15158		DELETE
H01L 2924/15159		DELETE
H01L 2924/15162		DELETE
H01L 2924/15165		DELETE
H01L 2924/1517		DELETE
H01L 2924/15172		DELETE
H01L 2924/15173		DELETE
H01L 2924/15174		DELETE
H01L 2924/15182		DELETE
H01L 2924/15183		DELETE
H01L 2924/15184		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2924/15192		DELETE
H01L 2924/152		DELETE
H01L 2924/153		DELETE
H01L 2924/1531		DELETE
H01L 2924/15311		DELETE
H01L 2924/15312		DELETE
H01L 2924/15313		DELETE
H01L 2924/1532		DELETE
H01L 2924/15321		DELETE
H01L 2924/15322		DELETE
H01L 2924/15323		DELETE
H01L 2924/1533		DELETE
H01L 2924/15331		DELETE
H01L 2924/15332		DELETE
H01L 2924/15333		DELETE
H01L 2924/156		DELETE
H01L 2924/157		DELETE
H01L 2924/15701		DELETE
H01L 2924/15717		DELETE
H01L 2924/15724		DELETE
H01L 2924/15738		DELETE
H01L 2924/15747		DELETE
H01L 2924/1576		DELETE
H01L 2924/15763		DELETE
H01L 2924/15786		DELETE
H01L 2924/15787		DELETE
H01L 2924/15788		DELETE
H01L 2924/1579		DELETE
H01L 2924/15791		DELETE
H01L 2924/15793		DELETE
H01L 2924/15798		DELETE
H01L 2924/161		DELETE
H01L 2924/1611		DELETE
H01L 2924/1615		DELETE
H01L 2924/16151		DELETE
H01L 2924/16152		DELETE
H01L 2924/16153		DELETE
H01L 2924/1616		DELETE
H01L 2924/1617		DELETE
H01L 2924/16171		DELETE
H01L 2924/16172		DELETE
H01L 2924/16173		DELETE
H01L 2924/16174		DELETE
H01L 2924/16175		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2924/16176		DELETE
H01L 2924/16177		DELETE
H01L 2924/16178		DELETE
H01L 2924/16179		DELETE
H01L 2924/1619		DELETE
H01L 2924/16195		DELETE
H01L 2924/16196		DELETE
H01L 2924/162		DELETE
H01L 2924/16235		DELETE
H01L 2924/16251		DELETE
H01L 2924/1626		DELETE
H01L 2924/1627		DELETE
H01L 2924/163		DELETE
H01L 2924/1631		DELETE
H01L 2924/16315		DELETE
H01L 2924/1632		DELETE
H01L 2924/164		DELETE
H01L 2924/165		DELETE
H01L 2924/16586		DELETE
H01L 2924/16587		DELETE
H01L 2924/16588		DELETE
H01L 2924/1659		DELETE
H01L 2924/16593		DELETE
H01L 2924/16598		DELETE
H01L 2924/166		DELETE
H01L 2924/167		DELETE
H01L 2924/16701		DELETE
H01L 2924/16717		DELETE
H01L 2924/16724		DELETE
H01L 2924/16738		DELETE
H01L 2924/16747		DELETE
H01L 2924/1676		DELETE
H01L 2924/16763		DELETE
H01L 2924/16786		DELETE
H01L 2924/16787		DELETE
H01L 2924/16788		DELETE
H01L 2924/1679		DELETE
H01L 2924/16791		DELETE
H01L 2924/16793		DELETE
H01L 2924/16798		DELETE
H01L 2924/171		DELETE
H01L 2924/1711		DELETE
H01L 2924/1715		DELETE
H01L 2924/17151		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2924/172		DELETE
H01L 2924/173		DELETE
H01L 2924/176		DELETE
H01L 2924/177		DELETE
H01L 2924/17701		DELETE
H01L 2924/17717		DELETE
H01L 2924/17724		DELETE
H01L 2924/17738		DELETE
H01L 2924/17747		DELETE
H01L 2924/1776		DELETE
H01L 2924/17763		DELETE
H01L 2924/17786		DELETE
H01L 2924/17787		DELETE
H01L 2924/17788		DELETE
H01L 2924/1779		DELETE
H01L 2924/17791		DELETE
H01L 2924/17793		DELETE
H01L 2924/17798		DELETE
H01L 2924/181		DELETE
H01L 2924/1811		DELETE
H01L 2924/1815		DELETE
H01L 2924/1816		DELETE
H01L 2924/18161		DELETE
H01L 2924/18162		DELETE
H01L 2924/18165		DELETE
H01L 2924/182		DELETE
H01L 2924/183		DELETE
H01L 2924/18301		DELETE
H01L 2924/186		DELETE
H01L 2924/19		DELETE
H01L 2924/1901		DELETE
H01L 2924/19011		DELETE
H01L 2924/19015		DELETE
H01L 2924/1902		DELETE
H01L 2924/1903		DELETE
H01L 2924/19031		DELETE
H01L 2924/19032		DELETE
H01L 2924/19033		DELETE
H01L 2924/19038		DELETE
H01L 2924/19039		DELETE
H01L 2924/1904		DELETE
H01L 2924/19041		DELETE
H01L 2924/19042		DELETE
H01L 2924/19043		DELETE

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H01L 2924/1905		DELETE
H01L 2924/19051		DELETE
H01L 2924/191		DELETE
H01L 2924/19101		DELETE
H01L 2924/19102		DELETE
H01L 2924/19103		DELETE
H01L 2924/19104		DELETE
H01L 2924/19105		DELETE
H01L 2924/19106		DELETE
H01L 2924/19107		DELETE
H01L 2924/20		DELETE
H01L 2924/201		DELETE
H01L 2924/20101		DELETE
H01L 2924/20102		DELETE
H01L 2924/20103		DELETE
H01L 2924/20104		DELETE
H01L 2924/20105		DELETE
H01L 2924/20106		DELETE
H01L 2924/20107		DELETE
H01L 2924/20108		DELETE
H01L 2924/20109		DELETE
H01L 2924/2011		DELETE
H01L 2924/20111		DELETE
H01L 2924/202		DELETE
H01L 2924/20201		DELETE
H01L 2924/20202		DELETE
H01L 2924/2021		DELETE
H01L 2924/20211		DELETE
H01L 2924/20212		DELETE
H01L 2924/20213		DELETE
H01L 2924/2024		DELETE
H01L 2924/2026		DELETE
H01L 2924/20261		DELETE
H01L 2924/20262		DELETE
H01L 2924/20263		DELETE
H01L 2924/2027		DELETE
H01L 2924/20271		DELETE
H01L 2924/203		DELETE
H01L 2924/20301		DELETE
H01L 2924/20302		DELETE
H01L 2924/20303		DELETE
H01L 2924/20304		DELETE
H01L 2924/20305		DELETE
H01L 2924/20306		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2924/20307		DELETE
H01L 2924/20308		DELETE
H01L 2924/20309		DELETE
H01L 2924/206		DELETE
H01L 2924/2064		DELETE
H01L 2924/20641		DELETE
H01L 2924/20642		DELETE
H01L 2924/20643		DELETE
H01L 2924/20644		DELETE
H01L 2924/20645		DELETE
H01L 2924/20646		DELETE
H01L 2924/20647		DELETE
H01L 2924/20648		DELETE
H01L 2924/20649		DELETE
H01L 2924/2065		DELETE
H01L 2924/20651		DELETE
H01L 2924/20652		DELETE
H01L 2924/20653		DELETE
H01L 2924/20654		DELETE
H01L 2924/20655		DELETE
H01L 2924/20656		DELETE
H01L 2924/20657		DELETE
H01L 2924/20658		DELETE
H01L 2924/207		DELETE
H01L 2924/2075		DELETE
H01L 2924/20751		DELETE
H01L 2924/20752		DELETE
H01L 2924/20753		DELETE
H01L 2924/20754		DELETE
H01L 2924/20755		DELETE
H01L 2924/20756		DELETE
H01L 2924/20757		DELETE
H01L 2924/20758		DELETE
H01L 2924/20759		DELETE
H01L 2924/2076		DELETE
H01L 2924/30		DELETE
H01L 2924/301		DELETE
H01L 2924/30101		DELETE
H01L 2924/30105		DELETE
H01L 2924/30107		DELETE
H01L 2924/3011		DELETE
H01L 2924/30111		DELETE
H01L 2924/302		DELETE
H01L 2924/30201		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2924/30205		DELETE
H01L 2924/3025		DELETE
H01L 2924/35		DELETE
H01L 2924/351		DELETE
H01L 2924/3511		DELETE
H01L 2924/3512		DELETE
H01L 2924/35121		DELETE
H01L 2924/36		DELETE
H01L 2924/364		DELETE
H01L 2924/3641		DELETE
H01L 2924/365		DELETE
H01L 2924/3651		DELETE
H01L 2924/36511		DELETE
H01L 2924/3656		DELETE
H01L 2924/37		DELETE
H01L 2924/37001		DELETE
H01L 2924/37002		DELETE
H01L 2924/3701		DELETE
H01L 2924/38		DELETE
H01L 2924/381		DELETE
H01L 2924/384		DELETE
H01L 2924/3841		DELETE
H01L 2924/386		DELETE
H01L 2924/3861		DELETE
H01L 2924/3862		DELETE
H01L 2924/40		DELETE
H01L 2924/401		DELETE
H01L 2924/40101		DELETE
H01L 2924/40102		DELETE
H01L 2924/40103		DELETE
H01L 2924/40105		DELETE
H01L 2924/4015		DELETE
H01L 2924/402		DELETE
H01L 2924/40201		DELETE
H01L 2924/40202		DELETE
H01L 2924/40203		DELETE
H01L 2924/40207		DELETE
H01L 2924/4025		DELETE
H01L 2924/40251		DELETE
H01L 2924/40252		DELETE
H01L 2924/40253		DELETE
H01L 2924/40254		DELETE
H01L 2924/40255		DELETE
H01L 2924/403		DELETE

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H01L 2924/40301		DELETE
H01L 2924/40302		DELETE
H01L 2924/40303		DELETE
H01L 2924/40304		DELETE
H01L 2924/40305		DELETE
H01L 2924/40306		DELETE
H01L 2924/4035		DELETE
H01L 2924/404		DELETE
H01L 2924/40401		DELETE
H01L 2924/40402		DELETE
H01L 2924/40403		DELETE
H01L 2924/40404		DELETE
H01L 2924/40405		DELETE
H01L 2924/40406		DELETE
H01L 2924/40407		DELETE
H01L 2924/405		DELETE
H01L 2924/40501		DELETE
H01L 2924/40502		DELETE
H01L 2924/40503	H10W 10/00	DELETE
H10W 10/00	H10W 10/00	NEW
H10W 10/01	H10W 10/00	NEW
H10W 10/011	H10W 10/00	NEW
H10W 10/012	H10W 10/00	NEW
H10W 10/0121	H10W 10/00	NEW
H10W 10/0123	H10W 10/00	NEW
H10W 10/0124	H10W 10/00	NEW
H10W 10/0125	H10W 10/00	NEW
H10W 10/0126	H10W 10/00	NEW
H10W 10/0127	H10W 10/00	NEW
H10W 10/0128	H10W 10/00	NEW
H10W 10/014	H10W 10/00	NEW
H10W 10/0142	H10W 10/00	NEW
H10W 10/0143	H10W 10/00	NEW
H10W 10/0145	H10W 10/00	NEW
H10W 10/0147	H10W 10/00	NEW
H10W 10/0148	H10W 10/00	NEW
H10W 10/018	H10W 10/00	NEW
H10W 10/019	H10W 10/00	NEW
H10W 10/021	H10W 10/00	NEW
H10W 10/031	H10W 10/00	NEW
H10W 10/041	H10W 10/00	NEW
H10W 10/051	H10W 10/00	NEW
H10W 10/061	H10W 10/00	NEW
H10W 10/10	H10W 10/10	NEW

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H10W 10/13	H10W 10/13	NEW
H10W 10/17	H10W 10/17	NEW
H10W 10/181	H10W 10/10	NEW
H10W 10/20	H10W 10/20	NEW
H10W 10/30	H10W 10/30	NEW
H10W 10/40	H10W 10/40	NEW
H10W 10/50	H10W 10/50	NEW
H10W 15/00	H10W 15/00	NEW
H10W 15/01	H10W 15/00	NEW
H10W 20/00	H10W 20/00	NEW
H10W 20/01	H10W 20/00	NEW
H10W 20/021	H10W 20/00	NEW
H10W 20/023	H10W 20/00	NEW
H10W 20/0234	H10W 20/00	NEW
H10W 20/0238	H10W 20/00	NEW
H10W 20/0242	H10W 20/00	NEW
H10W 20/0245	H10W 20/00	NEW
H10W 20/0249	H10W 20/00	NEW
H10W 20/0253	H10W 20/00	NEW
H10W 20/0257	H10W 20/00	NEW
H10W 20/0261	H10W 20/00	NEW
H10W 20/0265	H10W 20/00	NEW
H10W 20/031	H10W 20/00	NEW
H10W 20/032	H10W 20/00	NEW
H10W 20/033	H10W 20/00	NEW
H10W 20/034	H10W 20/00	NEW
H10W 20/035	H10W 20/00	NEW
H10W 20/036	H10W 20/00	NEW
H10W 20/037	H10W 20/00	NEW
H10W 20/0372	H10W 20/00	NEW
H10W 20/0375	H10W 20/00	NEW
H10W 20/038	H10W 20/00	NEW
H10W 20/039	H10W 20/00	NEW
H10W 20/041	H10W 20/00	NEW
H10W 20/042	H10W 20/00	NEW
H10W 20/0425	H10W 20/00	NEW
H10W 20/043	H10W 20/00	NEW
H10W 20/044	H10W 20/00	NEW
H10W 20/045	H10W 20/00	NEW
H10W 20/046	H10W 20/00	NEW
H10W 20/047	H10W 20/00	NEW
H10W 20/048	H10W 20/00	NEW
H10W 20/049	H10W 20/00	NEW
H10W 20/051	H10W 20/00	NEW

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H10W 20/052	H10W 20/00	NEW
H10W 20/0523	H10W 20/00	NEW
H10W 20/0526	H10W 20/00	NEW
H10W 20/054	H10W 20/00	NEW
H10W 20/055	H10W 20/00	NEW
H10W 20/0552	H10W 20/00	NEW
H10W 20/0554	H10W 20/00	NEW
H10W 20/056	H10W 20/00	NEW
H10W 20/057	H10W 20/00	NEW
H10W 20/058	H10W 20/00	NEW
H10W 20/059	H10W 20/00	NEW
H10W 20/0595	H10W 20/00	NEW
H10W 20/062	H10W 20/00	NEW
H10W 20/063	H10W 20/00	NEW
H10W 20/0633	H10W 20/00	NEW
H10W 20/0636	H10W 20/00	NEW
H10W 20/064	H10W 20/00	NEW
H10W 20/065	H10W 20/00	NEW
H10W 20/066	H10W 20/00	NEW
H10W 20/067	H10W 20/00	NEW
H10W 20/068	H10W 20/00	NEW
H10W 20/069	H10W 20/00	NEW
H10W 20/0693	H10W 20/00	NEW
H10W 20/0696	H10W 20/00	NEW
H10W 20/0698	H10W 20/00	NEW
H10W 20/071	H10W 20/00	NEW
H10W 20/072	H10W 20/00	NEW
H10W 20/074	H10W 20/00	NEW
H10W 20/075	H10W 20/00	NEW
H10W 20/076	H10W 20/00	NEW
H10W 20/0765	H10W 20/00	NEW
H10W 20/077	H10W 20/00	NEW
H10W 20/081	H10W 20/00	NEW
H10W 20/082	H10W 20/00	NEW
H10W 20/083	H10W 20/00	NEW
H10W 20/084	H10W 20/00	NEW
H10W 20/085	H10W 20/00	NEW
H10W 20/086	H10W 20/00	NEW
H10W 20/087	H10W 20/00	NEW
H10W 20/088	H10W 20/00	NEW
H10W 20/0882	H10W 20/00	NEW
H10W 20/0884	H10W 20/00	NEW
H10W 20/0886	H10W 20/00	NEW
H10W 20/0888	H10W 20/00	NEW

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H10W 20/089	H10W 20/00	NEW
H10W 20/091	H10W 20/00	NEW
H10W 20/092	H10W 20/00	NEW
H10W 20/093	H10W 20/00	NEW
H10W 20/094	H10W 20/00	NEW
H10W 20/095	H10W 20/00	NEW
H10W 20/096	H10W 20/00	NEW
H10W 20/097	H10W 20/00	NEW
H10W 20/098	H10W 20/00	NEW
H10W 20/20	H10W 20/20	NEW
H10W 20/211	H10W 20/20	NEW
H10W 20/212	H10W 20/20	NEW
H10W 20/2125	H10W 20/20	NEW
H10W 20/2128	H10W 20/20	NEW
H10W 20/213	H10W 20/20	NEW
H10W 20/2134	H10W 20/20	NEW
H10W 20/215	H10W 20/20	NEW
H10W 20/216	H10W 20/20	NEW
H10W 20/217	H10W 20/20	NEW
H10W 20/218	H10W 20/20	NEW
H10W 20/222	H10W 20/20	NEW
H10W 20/233	H10W 20/20	NEW
H10W 20/40	H10W 20/40	NEW
H10W 20/41	H10W 20/41	NEW
H10W 20/42	H10W 20/42	NEW
H10W 20/421	H10W 20/42	NEW
H10W 20/422	H10W 20/42	NEW
H10W 20/423	H10W 20/41	NEW
H10W 20/425	H10W 20/41	NEW
H10W 20/427	H10W 20/41	NEW
H10W 20/43	H10W 20/43	NEW
H10W 20/432	H10W 20/43	NEW
H10W 20/435	H10W 20/41	NEW
H10W 20/438	H10W 20/41	NEW
H10W 20/44	H10W 20/44	NEW
H10W 20/4403	H10W 20/44	NEW
H10W 20/4405	H10W 20/44	NEW
H10W 20/4407	H10W 20/44	NEW
H10W 20/4421	H10W 20/44	NEW
H10W 20/4424	H10W 20/44	NEW
H10W 20/4432	H10W 20/44	NEW
H10W 20/4435	H10W 20/44	NEW
H10W 20/4437	H10W 20/44	NEW
H10W 20/4441	H10W 20/44	NEW

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H10W 20/4446	H10W 20/44	NEW
H10W 20/4451	H10W 20/44	NEW
H10W 20/4462	H10W 20/44	NEW
H10W 20/4473	H10W 20/44	NEW
H10W 20/4484	H10W 20/44	NEW
H10W 20/45	H10W 20/45	NEW
H10W 20/455	H10W 20/45	NEW
H10W 20/46	H10W 20/46	NEW
H10W 20/47	H10W 20/47	NEW
H10W 20/48	H10W 20/48	NEW
H10W 20/481	H10W 20/40	NEW
H10W 20/482	H10W 20/40	NEW
H10W 20/483	H10W 20/40	NEW
H10W 20/484	H10W 20/40	NEW
H10W 20/49	H10W 20/49	NEW
H10W 20/491	H10W 20/49	NEW
H10W 20/492	H10W 20/49	NEW
H10W 20/493	H10W 20/49	NEW
H10W 20/494	H10W 20/49	NEW
H10W 20/495	H10W 20/40	NEW
H10W 20/496	H10W 20/40	NEW
H10W 20/497	H10W 20/40	NEW
H10W 20/498	H10W 20/40	NEW
H10W 29/00	H10W 29/00	NEW
H10W 29/01	H10W 29/00	NEW
H10W 40/00	H10W 40/00	NEW
H10W 40/01	H10W 40/00	NEW
H10W 40/03	H10W 40/00	NEW
H10W 40/033	H10W 40/00	NEW
H10W 40/037	H10W 40/00	NEW
H10W 40/10	H10W 40/10	NEW
H10W 40/20	H10W 40/20	NEW
H10W 40/22	H10W 40/22	NEW
H10W 40/226	H10W 40/22	NEW
H10W 40/228	H10W 40/22	NEW
H10W 40/231	H10W 40/20	NEW
H10W 40/233	H10W 40/20	NEW
H10W 40/235	H10W 40/20	NEW
H10W 40/237	H10W 40/20	NEW
H10W 40/242	H10W 40/20	NEW
H10W 40/25	H10W 40/25	NEW
H10W 40/251	H10W 40/25	NEW
H10W 40/253	H10W 40/25	NEW
H10W 40/254	H10W 40/25	NEW

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H10W 40/255	H10W 40/25	NEW
H10W 40/257	H10W 40/25	NEW
H10W 40/258	H10W 40/25	NEW
H10W 40/259	H10W 40/25	NEW
H10W 40/28	H10W 40/28	NEW
H10W 40/30	H10W 40/30	NEW
H10W 40/305	H10W 40/30	NEW
H10W 40/40	H10W 40/40	NEW
H10W 40/43	H10W 40/43	NEW
H10W 40/47	H10W 40/47	NEW
H10W 40/475	H10W 40/47	NEW
H10W 40/50	H10W 40/50	NEW
H10W 40/60	H10W 40/60	NEW
H10W 40/611	H10W 40/60	NEW
H10W 40/613	H10W 40/60	NEW
H10W 40/625	H10W 40/60	NEW
H10W 40/641	H10W 40/60	NEW
H10W 40/70	H10W 40/70	NEW
H10W 40/73	H10W 40/73	NEW
H10W 40/735	H10W 40/73	NEW
H10W 40/77	H10W 40/77	NEW
H10W 40/772	H10W 40/77	NEW
H10W 40/774	H10W 40/77	NEW
H10W 40/776	H10W 40/77	NEW
H10W 40/778	H10W 40/77	NEW
H10W 40/80	H10W 40/80	NEW
H10W 42/00	H10W 42/00	NEW
H10W 42/101	H10W 42/00	NEW
H10W 42/121	H10W 42/00	NEW
H10W 42/20	H10W 42/20	NEW
H10W 42/25	H10W 42/25	NEW
H10W 42/261	H10W 42/20	NEW
H10W 42/263	H10W 42/20	NEW
H10W 42/265	H10W 42/20	NEW
H10W 42/267	H10W 42/20	NEW
H10W 42/271	H10W 42/20	NEW
H10W 42/273	H10W 42/20	NEW
H10W 42/276	H10W 42/20	NEW
H10W 42/281	H10W 42/20	NEW
H10W 42/284	H10W 42/20	NEW
H10W 42/287	H10W 42/20	NEW
H10W 42/40	H10W 42/40	NEW
H10W 42/405	H10W 42/40	NEW
H10W 42/60	H10W 42/60	NEW

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H10W 42/80	H10W 42/80	NEW
H10W 44/00	H10W 44/00	NEW
H10W 44/20	H10W 44/20	NEW
H10W 44/203	H10W 44/20	NEW
H10W 44/206	H10W 44/20	NEW
H10W 44/209	H10W 44/20	NEW
H10W 44/212	H10W 44/20	NEW
H10W 44/216	H10W 44/20	NEW
H10W 44/219	H10W 44/20	NEW
H10W 44/223	H10W 44/20	NEW
H10W 44/226	H10W 44/20	NEW
H10W 44/231	H10W 44/20	NEW
H10W 44/234	H10W 44/20	NEW
H10W 44/241	H10W 44/20	NEW
H10W 44/243	H10W 44/20	NEW
H10W 44/248	H10W 44/20	NEW
H10W 44/251	H10W 44/20	NEW
H10W 44/255	H10W 44/20	NEW
H10W 44/259	H10W 44/20	NEW
H10W 44/401	H10W 44/00	NEW
H10W 44/501	H10W 44/00	NEW
H10W 44/601	H10W 44/00	NEW
H10W 46/00	H10W 46/00	NEW
H10W 46/101	H10W 46/00	NEW
H10W 46/103	H10W 46/00	NEW
H10W 46/106	H10W 46/00	NEW
H10W 46/201	H10W 46/00	NEW
H10W 46/301	H10W 46/00	NEW
H10W 46/401	H10W 46/00	NEW
H10W 46/403	H10W 46/00	NEW
H10W 46/407	H10W 46/00	NEW
H10W 46/501	H10W 46/00	NEW
H10W 46/503	H10W 46/00	NEW
H10W 46/507	H10W 46/00	NEW
H10W 46/601	H10W 46/00	NEW
H10W 46/603	H10W 46/00	NEW
H10W 46/607	H10W 46/00	NEW
H10W 70/00	H10W 70/00	NEW
H10W 70/01	H10W 70/01	NEW
H10W 70/02	H10W 70/02	NEW
H10W 70/023	H10W 70/02	NEW
H10W 70/027	H10W 70/02	NEW
H10W 70/04	H10W 70/04	NEW
H10W 70/041	H10W 70/04	NEW

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H10W 70/042	H10W 70/04	NEW
H10W 70/045	H10W 70/04	NEW
H10W 70/047	H10W 70/04	NEW
H10W 70/048	H10W 70/04	NEW
H10W 70/05	H10W 70/05	NEW
H10W 70/06	H10W 70/06	NEW
H10W 70/08	H10W 70/08	NEW
H10W 70/09	H10W 70/09	NEW
H10W 70/092	H10W 70/05	NEW
H10W 70/093	H10W 70/05	NEW
H10W 70/095	H10W 70/05	NEW
H10W 70/096	H10W 70/05	NEW
H10W 70/097	H10W 70/05	NEW
H10W 70/098	H10W 70/05	NEW
H10W 70/099	H10W 70/00	NEW
H10W 70/20	H10W 70/20	NEW
H10W 70/22	H10W 70/20	NEW
H10W 70/24	H10W 70/20	NEW
H10W 70/26	H10W 70/20	NEW
H10W 70/28	H10W 70/20	NEW
H10W 70/40	H10W 70/40	NEW
H10W 70/411	H10W 70/40	NEW
H10W 70/413	H10W 70/40	NEW
H10W 70/415	H10W 70/40	NEW
H10W 70/417	H10W 70/40	NEW
H10W 70/421	H10W 70/40	NEW
H10W 70/424	H10W 70/40	NEW
H10W 70/427	H10W 70/40	NEW
H10W 70/429	H10W 70/40	NEW
H10W 70/433	H10W 70/40	NEW
H10W 70/435	H10W 70/40	NEW
H10W 70/438	H10W 70/40	NEW
H10W 70/442	H10W 70/40	NEW
H10W 70/451	H10W 70/40	NEW
H10W 70/453	H10W 70/40	NEW
H10W 70/456	H10W 70/40	NEW
H10W 70/457	H10W 70/40	NEW
H10W 70/458	H10W 70/40	NEW
H10W 70/461	H10W 70/40	NEW
H10W 70/464	H10W 70/40	NEW
H10W 70/465	H10W 70/40	NEW
H10W 70/466	H10W 70/40	NEW
H10W 70/467	H10W 70/40	NEW
H10W 70/468	H10W 70/40	NEW

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H10W 70/474	H10W 70/40	NEW
H10W 70/475	H10W 70/40	NEW
H10W 70/476	H10W 70/40	NEW
H10W 70/479	H10W 70/40	NEW
H10W 70/481	H10W 70/40	NEW
H10W 70/60	H10W 70/60	NEW
H10W 70/611	H10W 70/60	NEW
H10W 70/614	H10W 70/60	NEW
H10W 70/616	H10W 70/60	NEW
H10W 70/618	H10W 70/60	NEW
H10W 70/62	H10W 70/62	NEW
H10W 70/63	H10W 70/63	NEW
H10W 70/635	H10W 70/63	NEW
H10W 70/641	H10W 70/62	NEW
H10W 70/644	H10W 70/62	NEW
H10W 70/65	H10W 70/65	NEW
H10W 70/652	H10W 70/652	NEW
H10W 70/6523	H10W 70/652	NEW
H10W 70/6525	H10W 70/652	NEW
H10W 70/6528	H10W 70/652	NEW
H10W 70/654	H10W 70/654	NEW
H10W 70/655	H10W 70/655	NEW
H10W 70/656	H10W 70/656	NEW
H10W 70/6565	H10W 70/65	NEW
H10W 70/657	H10W 70/65	NEW
H10W 70/658	H10W 70/65	NEW
H10W 70/66	H10W 70/66	NEW
H10W 70/662	H10W 70/66	NEW
H10W 70/664	H10W 70/66	NEW
H10W 70/666	H10W 70/66	NEW
H10W 70/668	H10W 70/66	NEW
H10W 70/67	H10W 70/67	NEW
H10W 70/68	H10W 70/68	NEW
H10W 70/681	H10W 70/68	NEW
H10W 70/682	H10W 70/68	NEW
H10W 70/685	H10W 70/685	NEW
H10W 70/686	H10W 70/685	NEW
H10W 70/687	H10W 70/685	NEW
H10W 70/6875	H10W 70/68	NEW
H10W 70/688	H10W 70/67	NEW
H10W 70/69	H10W 70/69	NEW
H10W 70/692	H10W 70/692	NEW
H10W 70/695	H10W 70/695	NEW
H10W 70/698	H10W 70/698	NEW

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H10W 70/699	H10W 70/60	NEW
H10W 72/00	H10W 72/00	NEW
H10W 72/01	H10W 72/00	NEW
H10W 72/011	H10W 72/00	NEW
H10W 72/0112	H10W 72/00	NEW
H10W 72/0113	H10W 72/00	NEW
H10W 72/0115	H10W 72/00	NEW
H10W 72/0116	H10W 72/00	NEW
H10W 72/012	H10W 72/00	NEW
H10W 72/01204	H10W 72/00	NEW
H10W 72/01208	H10W 72/00	NEW
H10W 72/01212	H10W 72/00	NEW
H10W 72/01215	H10W 72/00	NEW
H10W 72/01221	H10W 72/00	NEW
H10W 72/01223	H10W 72/00	NEW
H10W 72/01225	H10W 72/00	NEW
H10W 72/01231	H10W 72/00	NEW
H10W 72/01233	H10W 72/00	NEW
H10W 72/01235	H10W 72/00	NEW
H10W 72/01236	H10W 72/00	NEW
H10W 72/01238	H10W 72/00	NEW
H10W 72/01251	H10W 72/00	NEW
H10W 72/01253	H10W 72/00	NEW
H10W 72/01255	H10W 72/00	NEW
H10W 72/01257	H10W 72/00	NEW
H10W 72/01261	H10W 72/00	NEW
H10W 72/01265	H10W 72/00	NEW
H10W 72/01271	H10W 72/00	NEW
H10W 72/013	H10W 72/00	NEW
H10W 72/01304	H10W 72/00	NEW
H10W 72/01308	H10W 72/00	NEW
H10W 72/01315	H10W 72/00	NEW
H10W 72/01321	H10W 72/00	NEW
H10W 72/01323	H10W 72/00	NEW
H10W 72/01325	H10W 72/00	NEW
H10W 72/01331	H10W 72/00	NEW
H10W 72/01333	H10W 72/00	NEW
H10W 72/01335	H10W 72/00	NEW
H10W 72/01336	H10W 72/00	NEW
H10W 72/01338	H10W 72/00	NEW
H10W 72/01351	H10W 72/00	NEW
H10W 72/01353	H10W 72/00	NEW
H10W 72/01355	H10W 72/00	NEW
H10W 72/01357	H10W 72/00	NEW

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H10W 72/01359	H10W 72/00	NEW
H10W 72/01361	H10W 72/00	NEW
H10W 72/01365	H10W 72/00	NEW
H10W 72/01371	H10W 72/00	NEW
H10W 72/014	H10W 72/00	NEW
H10W 72/015	H10W 72/00	NEW
H10W 72/01504	H10W 72/00	NEW
H10W 72/01515	H10W 72/00	NEW
H10W 72/01551	H10W 72/00	NEW
H10W 72/01553	H10W 72/00	NEW
H10W 72/01561	H10W 72/00	NEW
H10W 72/01565	H10W 72/00	NEW
H10W 72/01571	H10W 72/00	NEW
H10W 72/016	H10W 72/00	NEW
H10W 72/01604	H10W 72/00	NEW
H10W 72/01615	H10W 72/00	NEW
H10W 72/01651	H10W 72/00	NEW
H10W 72/01653	H10W 72/00	NEW
H10W 72/01661	H10W 72/00	NEW
H10W 72/01665	H10W 72/00	NEW
H10W 72/01671	H10W 72/00	NEW
H10W 72/019	H10W 72/00	NEW
H10W 72/01904	H10W 72/00	NEW
H10W 72/01908	H10W 72/00	NEW
H10W 72/01921	H10W 72/00	NEW
H10W 72/01923	H10W 72/00	NEW
H10W 72/01925	H10W 72/00	NEW
H10W 72/01931	H10W 72/00	NEW
H10W 72/01933	H10W 72/00	NEW
H10W 72/01935	H10W 72/00	NEW
H10W 72/01936	H10W 72/00	NEW
H10W 72/01938	H10W 72/00	NEW
H10W 72/01951	H10W 72/00	NEW
H10W 72/01953	H10W 72/00	NEW
H10W 72/01955	H10W 72/00	NEW
H10W 72/01961	H10W 72/00	NEW
H10W 72/01971	H10W 72/00	NEW
H10W 72/0198	H10W 72/00	NEW
H10W 72/071	H10W 72/00	NEW
H10W 72/0711	H10W 72/00	NEW
H10W 72/07113	H10W 72/00	NEW
H10W 72/07118	H10W 72/00	NEW
H10W 72/07125	H10W 72/00	NEW
H10W 72/07131	H10W 72/00	NEW

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H10W 72/07139	H10W 72/00	NEW
H10W 72/07141	H10W 72/00	NEW
H10W 72/07152	H10W 72/00	NEW
H10W 72/07163	H10W 72/00	NEW
H10W 72/07168	H10W 72/00	NEW
H10W 72/07173	H10W 72/00	NEW
H10W 72/07178	H10W 72/00	NEW
H10W 72/07183	H10W 72/00	NEW
H10W 72/07188	H10W 72/00	NEW
H10W 72/072	H10W 72/00	NEW
H10W 72/07202	H10W 72/00	NEW
H10W 72/07204	H10W 72/00	NEW
H10W 72/07207	H10W 72/00	NEW
H10W 72/07211	H10W 72/00	NEW
H10W 72/07221	H10W 72/00	NEW
H10W 72/07223	H10W 72/00	NEW
H10W 72/07227	H10W 72/00	NEW
H10W 72/07231	H10W 72/00	NEW
H10W 72/07232	H10W 72/00	NEW
H10W 72/07233	H10W 72/00	NEW
H10W 72/07234	H10W 72/00	NEW
H10W 72/07235	H10W 72/00	NEW
H10W 72/07236	H10W 72/00	NEW
H10W 72/07237	H10W 72/00	NEW
H10W 72/07241	H10W 72/00	NEW
H10W 72/07251	H10W 72/00	NEW
H10W 72/07252	H10W 72/00	NEW
H10W 72/07253	H10W 72/00	NEW
H10W 72/07254	H10W 72/00	NEW
H10W 72/07255	H10W 72/00	NEW
H10W 72/07261	H10W 72/00	NEW
H10W 72/073	H10W 72/00	NEW
H10W 72/07302	H10W 72/00	NEW
H10W 72/07304	H10W 72/00	NEW
H10W 72/07307	H10W 72/00	NEW
H10W 72/07311	H10W 72/00	NEW
H10W 72/07321	H10W 72/00	NEW
H10W 72/07323	H10W 72/00	NEW
H10W 72/07327	H10W 72/00	NEW
H10W 72/07331	H10W 72/00	NEW
H10W 72/07332	H10W 72/00	NEW
H10W 72/07333	H10W 72/00	NEW
H10W 72/07334	H10W 72/00	NEW
H10W 72/07335	H10W 72/00	NEW

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H10W 72/07336	H10W 72/00	NEW
H10W 72/07337	H10W 72/00	NEW
H10W 72/07338	H10W 72/00	NEW
H10W 72/07339	H10W 72/00	NEW
H10W 72/07341	H10W 72/00	NEW
H10W 72/07351	H10W 72/00	NEW
H10W 72/07352	H10W 72/00	NEW
H10W 72/07353	H10W 72/00	NEW
H10W 72/07354	H10W 72/00	NEW
H10W 72/07355	H10W 72/00	NEW
H10W 72/074	H10W 72/00	NEW
H10W 72/075	H10W 72/00	NEW
H10W 72/07502	H10W 72/00	NEW
H10W 72/07504	H10W 72/00	NEW
H10W 72/07507	H10W 72/00	NEW
H10W 72/07511	H10W 72/00	NEW
H10W 72/07521	H10W 72/00	NEW
H10W 72/07523	H10W 72/00	NEW
H10W 72/07527	H10W 72/00	NEW
H10W 72/07531	H10W 72/00	NEW
H10W 72/07532	H10W 72/00	NEW
H10W 72/07533	H10W 72/00	NEW
H10W 72/07535	H10W 72/00	NEW
H10W 72/07536	H10W 72/00	NEW
H10W 72/07537	H10W 72/00	NEW
H10W 72/07541	H10W 72/00	NEW
H10W 72/07551	H10W 72/00	NEW
H10W 72/07552	H10W 72/00	NEW
H10W 72/07553	H10W 72/00	NEW
H10W 72/07554	H10W 72/00	NEW
H10W 72/07555	H10W 72/00	NEW
H10W 72/076	H10W 72/00	NEW
H10W 72/07602	H10W 72/00	NEW
H10W 72/07604	H10W 72/00	NEW
H10W 72/07607	H10W 72/00	NEW
H10W 72/07611	H10W 72/00	NEW
H10W 72/07621	H10W 72/00	NEW
H10W 72/07623	H10W 72/00	NEW
H10W 72/07627	H10W 72/00	NEW
H10W 72/07631	H10W 72/00	NEW
H10W 72/07632	H10W 72/00	NEW
H10W 72/07633	H10W 72/00	NEW
H10W 72/07635	H10W 72/00	NEW
H10W 72/07636	H10W 72/00	NEW

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H10W 72/07637	H10W 72/00	NEW
H10W 72/07641	H10W 72/00	NEW
H10W 72/07651	H10W 72/00	NEW
H10W 72/07652	H10W 72/00	NEW
H10W 72/07653	H10W 72/00	NEW
H10W 72/07654	H10W 72/00	NEW
H10W 72/07655	H10W 72/00	NEW
H10W 72/077	H10W 72/00	NEW
H10W 72/20	H10W 72/20	NEW
H10W 72/221	H10W 72/20	NEW
H10W 72/222	H10W 72/20	NEW
H10W 72/223	H10W 72/20	NEW
H10W 72/224	H10W 72/20	NEW
H10W 72/225	H10W 72/20	NEW
H10W 72/227	H10W 72/20	NEW
H10W 72/228	H10W 72/20	NEW
H10W 72/231	H10W 72/20	NEW
H10W 72/232	H10W 72/20	NEW
H10W 72/234	H10W 72/20	NEW
H10W 72/235	H10W 72/20	NEW
H10W 72/237	H10W 72/20	NEW
H10W 72/241	H10W 72/20	NEW
H10W 72/242	H10W 72/20	NEW
H10W 72/244	H10W 72/20	NEW
H10W 72/245	H10W 72/20	NEW
H10W 72/247	H10W 72/20	NEW
H10W 72/248	H10W 72/20	NEW
H10W 72/251	H10W 72/20	NEW
H10W 72/252	H10W 72/20	NEW
H10W 72/2524	H10W 72/20	NEW
H10W 72/2528	H10W 72/20	NEW
H10W 72/253	H10W 72/20	NEW
H10W 72/255	H10W 72/20	NEW
H10W 72/257	H10W 72/20	NEW
H10W 72/261	H10W 72/20	NEW
H10W 72/263	H10W 72/20	NEW
H10W 72/265	H10W 72/20	NEW
H10W 72/267	H10W 72/20	NEW
H10W 72/281	H10W 72/20	NEW
H10W 72/283	H10W 72/20	NEW
H10W 72/285	H10W 72/20	NEW
H10W 72/287	H10W 72/20	NEW
H10W 72/29	H10W 72/29	NEW
H10W 72/30	H10W 72/30	NEW

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H10W 72/321	H10W 72/30	NEW
H10W 72/322	H10W 72/30	NEW
H10W 72/323	H10W 72/30	NEW
H10W 72/324	H10W 72/30	NEW
H10W 72/325	H10W 72/30	NEW
H10W 72/327	H10W 72/30	NEW
H10W 72/328	H10W 72/30	NEW
H10W 72/331	H10W 72/30	NEW
H10W 72/332	H10W 72/30	NEW
H10W 72/334	H10W 72/30	NEW
H10W 72/335	H10W 72/30	NEW
H10W 72/337	H10W 72/30	NEW
H10W 72/341	H10W 72/30	NEW
H10W 72/342	H10W 72/30	NEW
H10W 72/344	H10W 72/30	NEW
H10W 72/345	H10W 72/30	NEW
H10W 72/347	H10W 72/30	NEW
H10W 72/348	H10W 72/30	NEW
H10W 72/351	H10W 72/30	NEW
H10W 72/352	H10W 72/30	NEW
H10W 72/3524	H10W 72/30	NEW
H10W 72/3528	H10W 72/30	NEW
H10W 72/353	H10W 72/30	NEW
H10W 72/354	H10W 72/30	NEW
H10W 72/355	H10W 72/30	NEW
H10W 72/357	H10W 72/30	NEW
H10W 72/361	H10W 72/30	NEW
H10W 72/365	H10W 72/30	NEW
H10W 72/367	H10W 72/30	NEW
H10W 72/381	H10W 72/30	NEW
H10W 72/383	H10W 72/30	NEW
H10W 72/385	H10W 72/30	NEW
H10W 72/387	H10W 72/30	NEW
H10W 72/40	H10W 72/40	NEW
H10W 72/49	H10W 72/49	NEW
H10W 72/50	H10W 72/50	NEW
H10W 72/521	H10W 72/50	NEW
H10W 72/522	H10W 72/50	NEW
H10W 72/523	H10W 72/50	NEW
H10W 72/524	H10W 72/50	NEW
H10W 72/525	H10W 72/50	NEW
H10W 72/527	H10W 72/50	NEW
H10W 72/528	H10W 72/50	NEW
H10W 72/531	H10W 72/50	NEW

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H10W 72/533	H10W 72/50	NEW
H10W 72/534	H10W 72/50	NEW
H10W 72/535	H10W 72/50	NEW
H10W 72/536	H10W 72/50	NEW
H10W 72/5363	H10W 72/50	NEW
H10W 72/5366	H10W 72/50	NEW
H10W 72/5368	H10W 72/50	NEW
H10W 72/537	H10W 72/50	NEW
H10W 72/541	H10W 72/50	NEW
H10W 72/543	H10W 72/50	NEW
H10W 72/5434	H10W 72/50	NEW
H10W 72/5438	H10W 72/50	NEW
H10W 72/5445	H10W 72/50	NEW
H10W 72/5449	H10W 72/50	NEW
H10W 72/5453	H10W 72/50	NEW
H10W 72/547	H10W 72/50	NEW
H10W 72/5473	H10W 72/50	NEW
H10W 72/5475	H10W 72/50	NEW
H10W 72/551	H10W 72/50	NEW
H10W 72/552	H10W 72/50	NEW
H10W 72/5522	H10W 72/50	NEW
H10W 72/5524	H10W 72/50	NEW
H10W 72/5525	H10W 72/50	NEW
H10W 72/5527	H10W 72/50	NEW
H10W 72/5528	H10W 72/50	NEW
H10W 72/553	H10W 72/50	NEW
H10W 72/555	H10W 72/50	NEW
H10W 72/557	H10W 72/50	NEW
H10W 72/581	H10W 72/50	NEW
H10W 72/583	H10W 72/50	NEW
H10W 72/585	H10W 72/50	NEW
H10W 72/59	H10W 72/59	NEW
H10W 72/60	H10W 72/60	NEW
H10W 72/621	H10W 72/60	NEW
H10W 72/622	H10W 72/60	NEW
H10W 72/623	H10W 72/60	NEW
H10W 72/624	H10W 72/60	NEW
H10W 72/625	H10W 72/60	NEW
H10W 72/627	H10W 72/60	NEW
H10W 72/631	H10W 72/60	NEW
H10W 72/634	H10W 72/60	NEW
H10W 72/635	H10W 72/60	NEW
H10W 72/637	H10W 72/60	NEW
H10W 72/641	H10W 72/60	NEW

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H10W 72/642	H10W 72/60	NEW
H10W 72/643	H10W 72/60	NEW
H10W 72/644	H10W 72/60	NEW
H10W 72/645	H10W 72/60	NEW
H10W 72/646	H10W 72/60	NEW
H10W 72/647	H10W 72/60	NEW
H10W 72/6478	H10W 72/60	NEW
H10W 72/651	H10W 72/60	NEW
H10W 72/652	H10W 72/60	NEW
H10W 72/6524	H10W 72/60	NEW
H10W 72/6528	H10W 72/60	NEW
H10W 72/653	H10W 72/60	NEW
H10W 72/655	H10W 72/60	NEW
H10W 72/657	H10W 72/60	NEW
H10W 72/681	H10W 72/60	NEW
H10W 72/683	H10W 72/60	NEW
H10W 72/685	H10W 72/60	NEW
H10W 72/691	H10W 72/60	NEW
H10W 72/701	H10W 72/00	NEW
H10W 72/709	H10W 72/00	NEW
H10W 72/801	H10W 72/00	NEW
H10W 72/812	H10W 72/00	NEW
H10W 72/823	H10W 72/00	NEW
H10W 72/834	H10W 72/00	NEW
H10W 72/851	H10W 72/00	NEW
H10W 72/853	H10W 72/00	NEW
H10W 72/856	H10W 72/00	NEW
H10W 72/859	H10W 72/00	NEW
H10W 72/862	H10W 72/00	NEW
H10W 72/865	H10W 72/00	NEW
H10W 72/868	H10W 72/00	NEW
H10W 72/871	H10W 72/00	NEW
H10W 72/874	H10W 72/00	NEW
H10W 72/877	H10W 72/00	NEW
H10W 72/879	H10W 72/00	NEW
H10W 72/881	H10W 72/00	NEW
H10W 72/884	H10W 72/00	NEW
H10W 72/886	H10W 72/00	NEW
H10W 72/889	H10W 72/00	NEW
H10W 72/90	H10W 72/90	NEW
H10W 72/921	H10W 72/90	NEW
H10W 72/922	H10W 72/90	NEW
H10W 72/9223	H10W 72/90	NEW
H10W 72/9226	H10W 72/90	NEW

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H10W 72/923	H10W 72/90	NEW
H10W 72/9232	H10W 72/90	NEW
H10W 72/924	H10W 72/90	NEW
H10W 72/925	H10W 72/90	NEW
H10W 72/926	H10W 72/90	NEW
H10W 72/927	H10W 72/90	NEW
H10W 72/931	H10W 72/90	NEW
H10W 72/932	H10W 72/90	NEW
H10W 72/934	H10W 72/90	NEW
H10W 72/936	H10W 72/90	NEW
H10W 72/941	H10W 72/90	NEW
H10W 72/9413	H10W 72/90	NEW
H10W 72/9415	H10W 72/90	NEW
H10W 72/942	H10W 72/90	NEW
H10W 72/944	H10W 72/90	NEW
H10W 72/9445	H10W 72/90	NEW
H10W 72/951	H10W 72/90	NEW
H10W 72/952	H10W 72/90	NEW
H10W 72/9524	H10W 72/90	NEW
H10W 72/9528	H10W 72/90	NEW
H10W 72/953	H10W 72/90	NEW
H10W 72/957	H10W 72/90	NEW
H10W 72/961	H10W 72/90	NEW
H10W 72/963	H10W 72/90	NEW
H10W 72/965	H10W 72/90	NEW
H10W 72/967	H10W 72/90	NEW
H10W 72/981	H10W 72/90	NEW
H10W 72/983	H10W 72/90	NEW
H10W 72/985	H10W 72/90	NEW
H10W 72/987	H10W 72/90	NEW
H10W 74/00	H10W 74/00	NEW
H10W 74/01	H10W 74/01	NEW
H10W 74/012	H10W 74/01	NEW
H10W 74/014	H10W 74/01	NEW
H10W 74/016	H10W 74/01	NEW
H10W 74/017	H10W 74/01	NEW
H10W 74/019	H10W 74/01	NEW
H10W 74/10	H10W 74/10	NEW
H10W 74/111	H10W 74/10	NEW
H10W 74/114	H10W 74/10	NEW
H10W 74/117	H10W 74/10	NEW
H10W 74/121	H10W 74/10	NEW
H10W 74/124	H10W 74/10	NEW
H10W 74/127	H10W 74/10	NEW

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H10W 74/129	H10W 74/10	NEW
H10W 74/131	H10W 74/10	NEW
H10W 74/134	H10W 74/10	NEW
H10W 74/137	H10W 74/10	NEW
H10W 74/141	H10W 74/10	NEW
H10W 74/142	H10W 74/10	NEW
H10W 74/144	H10W 74/10	NEW
H10W 74/147	H10W 74/10	NEW
H10W 74/15	H10W 74/15	NEW
H10W 74/40	H10W 74/40	NEW
H10W 74/43	H10W 74/43	NEW
H10W 74/47	H10W 74/47	NEW
H10W 74/473	H10W 74/47	NEW
H10W 74/476	H10W 74/47	NEW
H10W 74/481	H10W 74/40	NEW
H10W 76/00	H10W 76/00	NEW
H10W 76/01	H10W 76/01	NEW
H10W 76/05	H10W 76/05	NEW
H10W 76/10	H10W 76/10	NEW
H10W 76/12	H10W 76/12	NEW
H10W 76/13	H10W 76/13	NEW
H10W 76/132	H10W 76/132	NEW
H10W 76/134	H10W 76/134	NEW
H10W 76/136	H10W 76/136	NEW
H10W 76/138	H10W 76/138	NEW
H10W 76/15	H10W 76/15	NEW
H10W 76/153	H10W 76/153	NEW
H10W 76/157	H10W 76/157	NEW
H10W 76/161	H10W 76/12	NEW
H10W 76/165	H10W 76/12	NEW
H10W 76/167	H10W 76/12	NEW
H10W 76/17	H10W 76/17	NEW
H10W 76/18	H10W 76/18	NEW
H10W 76/40	H10W 76/40	NEW
H10W 76/42	H10W 76/42	NEW
H10W 76/43	H10W 76/43	NEW
H10W 76/45	H10W 76/45	NEW
H10W 76/47	H10W 76/47	NEW
H10W 76/48	H10W 76/48	NEW
H10W 76/60	H10W 76/60	NEW
H10W 76/63	H10W 76/63	NEW
H10W 76/67	H10W 76/67	NEW
H10W 78/00	H10W 78/00	NEW
H10W 80/00	H10W 80/00	NEW

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H10W 80/011	H10W 80/00	NEW
H10W 80/016	H10W 80/00	NEW
H10W 80/023	H10W 80/00	NEW
H10W 80/031	H10W 80/00	NEW
H10W 80/033	H10W 80/00	NEW
H10W 80/035	H10W 80/00	NEW
H10W 80/037	H10W 80/00	NEW
H10W 80/041	H10W 80/00	NEW
H10W 80/102	H10W 80/00	NEW
H10W 80/161	H10W 80/00	NEW
H10W 80/163	H10W 80/00	NEW
H10W 80/165	H10W 80/00	NEW
H10W 80/168	H10W 80/00	NEW
H10W 80/211	H10W 80/00	NEW
H10W 80/301	H10W 80/00	NEW
H10W 80/312	H10W 80/00	NEW
H10W 80/314	H10W 80/00	NEW
H10W 80/327	H10W 80/00	NEW
H10W 80/331	H10W 80/00	NEW
H10W 80/333	H10W 80/00	NEW
H10W 80/334	H10W 80/00	NEW
H10W 80/335	H10W 80/00	NEW
H10W 80/337	H10W 80/00	NEW
H10W 80/338	H10W 80/00	NEW
H10W 80/339	H10W 80/00	NEW
H10W 80/341	H10W 80/00	NEW
H10W 80/701	H10W 80/00	NEW
H10W 80/721	H10W 80/00	NEW
H10W 80/732	H10W 80/00	NEW
H10W 80/743	H10W 80/00	NEW
H10W 80/754	H10W 80/00	NEW
H10W 90/00	H10W 90/00	NEW
H10W 90/10	H10W 90/10	NEW
H10W 90/15	H10W 90/15	NEW
H10W 90/155	H10W 90/15	NEW
H10W 90/20	H10W 90/20	NEW
H10W 90/22	H10W 90/22	NEW
H10W 90/231	H10W 90/20	NEW
H10W 90/24	H10W 90/24	NEW
H10W 90/26	H10W 90/26	NEW
H10W 90/271	H10W 90/20	NEW
H10W 90/275	H10W 90/20	NEW
H10W 90/28	H10W 90/28	NEW
H10W 90/284	H10W 90/20	NEW

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H10W 90/288	H10W 90/20	NEW
H10W 90/291	H10W 90/20	NEW
H10W 90/293	H10W 90/20	NEW
H10W 90/295	H10W 90/20	NEW
H10W 90/297	H10W 90/20	NEW
H10W 90/401	H10W 90/00	NEW
H10W 90/701	H10W 90/00	NEW
H10W 90/721	H10W 90/00	NEW
H10W 90/722	H10W 90/00	NEW
H10W 90/723	H10W 90/00	NEW
H10W 90/724	H10W 90/00	NEW
H10W 90/725	H10W 90/00	NEW
H10W 90/726	H10W 90/00	NEW
H10W 90/727	H10W 90/00	NEW
H10W 90/728	H10W 90/00	NEW
H10W 90/729	H10W 90/00	NEW
H10W 90/7295	H10W 90/00	NEW
H10W 90/731	H10W 90/00	NEW
H10W 90/732	H10W 90/00	NEW
H10W 90/733	H10W 90/00	NEW
H10W 90/734	H10W 90/00	NEW
H10W 90/735	H10W 90/00	NEW
H10W 90/736	H10W 90/00	NEW
H10W 90/737	H10W 90/00	NEW
H10W 90/738	H10W 90/00	NEW
H10W 90/739	H10W 90/00	NEW
H10W 90/751	H10W 90/00	NEW
H10W 90/752	H10W 90/00	NEW
H10W 90/753	H10W 90/00	NEW
H10W 90/754	H10W 90/00	NEW
H10W 90/755	H10W 90/00	NEW
H10W 90/756	H10W 90/00	NEW
H10W 90/757	H10W 90/00	NEW
H10W 90/758	H10W 90/00	NEW
H10W 90/759	H10W 90/00	NEW
H10W 90/761	H10W 90/00	NEW
H10W 90/762	H10W 90/00	NEW
H10W 90/763	H10W 90/00	NEW
H10W 90/764	H10W 90/00	NEW
H10W 90/765	H10W 90/00	NEW
H10W 90/766	H10W 90/00	NEW
H10W 90/767	H10W 90/00	NEW
H10W 90/768	H10W 90/00	NEW
H10W 90/769	H10W 90/00	NEW

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<u>CPC</u>	<u>IPC</u>	<u>Action*</u>
H10W 90/791	H10W 90/00	NEW
H10W 90/792	H10W 90/00	NEW
H10W 90/794	H10W 90/00	NEW
H10W 90/796	H10W 90/00	NEW
H10W 90/798	H10W 90/00	NEW
H10W 90/811	H10W 90/00	NEW
H10W 95/00	H10W 95/00	NEW
H10W 99/00	H10W 99/00	NEW

*Action column:

- For an (N) or (Q) entry, provide an IPC symbol and complete the Action column with “NEW.”
- For an existing CPC main trunk entry or indexing entry where the existing IPC symbol needs to be changed, provide an updated IPC symbol and complete the Action column with “UPDATED.”
- For a (D) CPC entry or indexing entry complete the Action column with “DELETE.” IPC symbol does not need to be included in the IPC column.
- For an (N) 2000 series CPC entry which is positioned within the main trunk scheme (breakdown code) provide an IPC symbol and complete the action column with “NEW”.
- For an (N) 2000 series CPC entry positioned at the end of the CPC scheme (orthogonal code), with no IPC equivalent, complete the IPC column with “CPCONLY” and complete the action column with “NEW”.

NOTES:

- F symbols are not included in the CICL table above.
- T and M symbols are not included in the CICL table above unless a change to the existing IPC is desired.

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5. CROSS-REFERENCE LIST (CRL)

Scheme references impacted by this revision project

<u>Location of reference to be changed</u>	<u>Referenced subclass or group to be changed</u>	<u>Action; New reference symbol; New text</u>
B81C 1/00507	H01L 21/762	H10W 10/10
G01R 31/2896	H01L 23/02	H10W 76/10
G01R 31/2896	H01L 23/28	H10W 74/00
G01R 33/0047	H01L 23/00	H10W 99/00
H05K 1/025	H01L 23/66	H10W 44/20
H05K 5/0091	H01L 23/00	H10W 99/00
H05K 9/0022	H01L 23/552	H10W 42/20
C04B 35/00	H01L 23/15	H10W 70/692
G02B 6/4232	H01L 24/81	H10W 72/072
G02B 6/425	H01L 25/0753	H10W 90/00
G02B 6/4268	H01L 23/24	H10W 76/47
G01J 5/045	H01L 23/26, H01L 21/3221	H10W 76/48, H10P 36/03
F25D 3/10	H01L 23/445	H10W 40/305
H01H 85/0241	H01L 23/5256	H10W 20/493
H01H 85/0241	H01L 23/62	H10W 42/80
G03F 9/7073	H01L 23/544	H10W 46/00
B21F 15/00	H01L 24/85	H10W 72/075
B21F 45/00	H01L 24/42	H10W 72/50
G01T 1/242	H01L 25/00	H10W 90/00
G01T 1/243	H01L 25/00	H10W 90/00

Definitions references impacted by this revision project

<u>Location of reference to be changed</u>	<u>Referenced subclass or group to be changed</u>	<u>Section of definition</u>	<u>Action; New reference symbol; New text</u>
A41D 1/002	H01L 23/5387	Informative references	H10W 70/688
B21C 37/04	H01L 24/42	Informative references	H10W 72/50
B21J 5/068	H01L 23/3672	Informative references	H10W 40/226
B29C 39/00	H01L 21/56	Informative references	H10W 74/01
B29C 39/00	H01L 23/28	Informative references	H10W 74/00
B29C 45/14655	H01L 21/565	Informative references	H10W 74/016
B29C 45/14655	H01L 21/67126	Informative references	H10P 72/0441

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<u>Location of reference to be changed</u>	<u>Referenced subclass or group to be changed</u>	<u>Section of definition</u>	<u>Action; New reference symbol; New text</u>
B29C 45/14655	H01L 21/565	Relationships with other classification places	H10W 74/016
B81B	H01L 21/30	Informative references	H10P 95/00
B81B	H01L 21/768	Informative references	H10W 20/01
B81B	H01L 23/544	Informative references	H10W 46/00
B81C	Acoustic emission sensors (symbol is missing)	Informative references	G01N 29/14
B81C	H01L 21/30	Informative references	H10P 95/00
B81C	H01L 21/768	Informative references	H10W 20/01
B81C	H01L 22/34	Informative references	H10P 74/277
C03C	H01L 23/488	Informative references	H10W 72/20
C04B 35/00	H01L 23/00	Informative references	H10W 99/00
C04B 35/00	H01L 23/15	Informative references	H10W 70/692
C04B 35/00	H01L 23/291	Informative references	H10W 74/43
C04B 35/56	H01L 23/291	Informative references	H10W 74/43
C04B 35/58	H01L 21/02389	Informative references	H10P 14/2908
C04B 35/58	H01L 21/02458, H01L 21/0254	Informative references	H10P 14/3216, H10P 14/3416
C04B 35/58	H01L 21/28202	Informative references	H10D 64/01344
C04B 35/58	H01L 21/3143	Informative references	H10P 14/662 (also remove the text “and subgroups” after the symbol)
C04B 35/58	H01L 21/318	Informative references	H10P 14/60
C04B 35/58	H01L 23/291	Informative references	H10W 74/43
C04B 35/58085	H01L 21/02425	Informative references	H10P 14/2923
C04B 35/58085	H01L 21/02425	Informative references	H10P 14/2923
C04B 35/58085	H01L 21/28052	Informative references	H10D 64/0131

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C04B 35/58085	H01L 21/28061	Informative references	H10D 64/01312
C04B 35/58085	H01L 21/28097	Informative references	H10D 64/0132
C04B 35/58085	H01L 21/28518	Informative references	H10D 64/0112
C04B 35/58085	H01L 21/28518	Informative references	H10D 64/0112
C04B 35/58085	H01L 21/32053	Informative references	H10P 14/414
C04B 35/58085	H01L 21/76889	Informative references	H10W 20/066
C04B 2235/96	H01L 23/00	Special rules of classification	H10W 99/00
C08G 77/00	H01L 21/3122, H01L 23/296	Informative references	H10P 14/68 H10W 74/476
C08L 83/00	H01L 21/3122, H01L 23/296	Informative references	H10P 14/68 H10W 74/476
C09G	H01L 21/02024	Informative references	H10P 90/129
C09G	H01L 21/304	Informative references	H10P 52/00
C09G	H01L 21/30625	Informative references	H10P 52/402
C09G	H01L 21/31051	Informative references	H10P 95/06
C09G	H01L 21/3212	Informative references	H10P 52/403
C09G	H01L 21/7684	Informative references	H10W 20/062
C09G	H01L 21/02041	Limiting references	H10P 70/00
C09G 1/00	H01L 21/304	Informative references	H10P 14/38
C09G 1/00	H01L 21/30625	Informative references	H10P 52/402
C09G 1/00	H01L 21/31053	Informative references	H10P 95/062
C09G 1/00	H01L 21/3212	Informative references	H10P 52/403
C09G 1/00	H01L 21/7684	Informative references	H10W 20/062
C09J 7/00	H01L 21/6836	Application- oriented references	H10P 72/7402
C09J 7/00	H01L 21/304, H01L 21/78	Application- oriented references	H10P 14/38, H10P 54/00

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C09J 7/00	H01L 24/83	Application-oriented references	H10W 72/073
C09J 7/00	H01L 21/00	Relationships with other classification places	H10P 95/00
F21K 9/00	H01L 25/0753	Informative references	H10W 90/00
F21V 29/00	H01L 23/34	Informative references	H10W 40/00
F24F	H01L 23/34	Informative references	H10W 40/00
F24F 5/0042	H01L 23/38	Informative references	H10W 40/28
F25D 3/10	H01L 23/445	Informative references	H10W 40/305
F28D	H01L 23/34	Limiting references	H10W 40/00
F28D	H01L 23/367	Limiting references	H10W 40/22
F28D	H01L 23/427	Limiting references	H10W 40/73
F28D	H01L 23/467	Limiting references	H10W 40/43
F28D	H01L 23/473	Limiting references	H10W 40/47
F28D 15/00	C03C 5/235	Informative references	C03B 5/235
F28D 15/00	H01L 23/427	Informative references	H10W 40/73
F28D 2021/0028	H01L 23/34	Informative references	H10W 40/00
F28F 3/00	H01L 23/36	Limiting references	H10W 40/10
F28F 3/00	H01L 23/367	Limiting references	H10W 40/22
F28F 13/00	H01L 23/373	Limiting references	H10W 40/25
F28F 13/00	H01L 23/4373	Limiting references	H10W 40/776
G01J 5/02	H01L 23/26	Informative references	<u>Delete</u> H01L 23/26 but <u>keep</u> B01D 53/0407.
G01K	H01L 23/38	Informative references	H10W 40/28
G01K 7/00	H01L 23/38	Informative references	H10W 40/28
G02B 6/42	H01L 23/66	Informative references	H10W 44/20

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G02F 1/01	H01L 25/00	Application- oriented references	H10W 90/00
G02F 1/13452	H01L 21/00	Informative references	H10P 95/00
G02F 1/13452	H01L 23/00	Informative references	H10W 99/00
G02F 1/13452	H01L 21/00	Relationships with other classification places	H10P 95/00
G06K 7/00	H01L 23/498, H01L 23/538	Informative references	H10W 70/60, H10W 70/611
G06K 19/00	H01L 23/00	Informative references	H10W 99/00
G06K 19/07327	H01L 23/576	Informative references	H10W 42/405
G06K 19/07743	G067K/00K	Informative references	G06K 7/00
G06K 19/07743	H01L 23/49855, H01L 23/5388	Informative references	H10W 70/699 H10W 70/611
G06K 19/07745	H01L23/25	Informative references	<u>Delete</u> the entire table row.
G06K 19/07745	H01L 23/28	Informative references	H10W 74/00
G06Q 20/105	H01L 23/58	Informative references	H10W 42/00
G06V 10/22	H01L 23/544	Application- oriented references	H10W 46/00
G09F	H01L 25/00, H10H 20/00	Informative references	H10W 90/00, H10H 20/00
G09F	G06F3/1446, H01L 25/10, H10K59/18, H05K5/30	Informative references	G06F3/1446, H10W 90/00, H10K59/18, H05K5/30
G09F 9/00	G06F3/1446, H01L 25/10, H05K5/30	Informative references	G06F3/1446, H10W 90/00, H05K5/30
G09F 9/00	H01L 25/00	Informative references	H10W 90/00
G11B 33/00	H05K7/20, F28D15/00, H04B1/036, G06F1/20, H01L 23/34	Informative references	H05K7/20, F28D15/00, H04B1/036, G06F1/20, H10W 40/00
G11C 5/00	H01L 21/26, G06F11/00	Informative references	H10P 34/00, G06F11/00

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G11C 5/00	H05K5/02, H01L 25/00	Informative references	H05K5/02, H10W 90/00
G12B 9/00	H01L 23/02, H01L 23/28	Informative references	H10W 76/10, H10W 74/00
H01F 17/00	H01L 23/645	Application-oriented references	H10W 44/501
H01F 17/00	H01L 23/5227	Informative references	H10W 20/497
H01J 31/00	G09F9/33, H01L 25/0753	Informative references	G09F9/33, H10W 90/00
H01J 37/00	H01L	Informative references	<u>Delete</u> entire H01L table row.
H01J 37/00	H01L 21/265	Informative references	H10P 30/20
H01J 37/00	H01L 21/76892	Informative references	H10W 20/067
H01J 37/00	H01L 22/00	Informative references	H10P 74/00
H01J 37/023	H01L 21/48	Informative references	H10W 99/00
H01J 37/3174	H01L 21/67005	Informative references	H10P 72/00
H01J 37/3174	H01L 21/677	Informative references	H10P 72/30
H01J 37/3174	H01L 22/00	Informative references	H10P 74/00
H01J 37/3174	H01L 23/544	Informative references	H10W 46/00
H01P 5/04	H01L 23/64	Relationships with other classification places	H10W 44/00
H01Q 1/2283	H01L 23/49855	Informative references	H10W 70/699
H01Q 21/0087	H01L21/00, H01L 23/00, H01L25/00	Glossary of terms	<u>Replace</u> existing symbols with new symbols H10P 95/00, H10W 99/00, H10W 90/00 <u>and delete the images and text</u> “See: US6168972, US2004217472, WO03050865”
H01S 5/00	H01L 21/02365	Relationships with other classification places	H10P 14/20

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H01S 5/00	H01L 23/34	Relationships with other classification places	H10W 40/00
H01S 5/00	H01L 25/00	Relationships with other classification places	H10W 90/00
H01S 5/022	H01L 23/00	Informative references	H10W 99/00
H01S 5/024	H01L 23/34	Informative references	H10W 40/00
H02H 9/00	H01L 23/62	Informative references	H10W 42/80
H02K 11/00	H01L 25/00	Informative references	H10W 90/00
H03F 3/189	H01L 23/66	Informative references	H10W 44/20
H03F 3/60	H01L 23/66	Informative references	H10W 44/20
H05F	H01L 23/60	Limiting references	H10W 42/60
H05F 3/00	H01L 23/60	Application- oriented references	H10W 42/60
H05K 1/00	H01L 25/00	Application- oriented references	H10W 90/00
H05K 1/00	H05K 13/0061, B65G, H01L 21/68	Informative references	H05K 13/0061, B65G, H10P 72/50
H05K 1/00	H01L 21/48, H01L23/00, H01L24/00	Informative references	H10W 99/00, H10W 72/00
H05K 1/00	H01L 23/66	Informative references	H10W 44/20
H05K 1/00	H01L 21/68	Informative references	H10P 72/50
H05K 1/00	H01L	Relationships with other classification places	<u>Delete</u> H01L and the comma that follows.
H05K 1/00	H01L 21/48, H01L23/00, H01L 25/00	Relationships with other classification places	H10W 99/00, H10W 90/00
H05K 1/025	H01L 23/64	Limiting references	H10W 44/00

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<u>Location of reference to be changed</u>	<u>Referenced subclass or group to be changed</u>	<u>Section of definition</u>	<u>Action; New reference symbol; New text</u>
H05K 1/025	H01L 23/66	Limiting references	H10W 44/20
H05K 1/03	H01L 23/00	Informative references	H10W 99/00
H05K 3/00	H01L 21/00	Informative references	H10P 95/00
H05K 3/00	H01L 21/48, H01L23/00, H01L 25/00	Relationships with other classification places	H10W 99/00, H10W 90/00
H05K 3/00	H01L	Relationships with other classification places	~~Delete~~ H01L and the comma that follows.
H05K 7/00	H01L 23/34	Application-oriented references	H10W 40/00
H05K 7/00	H01L 25/065	Informative references	H10W 90/00
H05K 7/20	H01L 23/34	Application-oriented references	H10W 40/00
H05K 9/00	H01L 23/552, H01L24/00	Application-oriented references	H10W 42/20, H10W 72/00
H05K 9/00	H01L 23/60	Application-oriented references	H10W 42/60
H10B 20/20	H01L 23/5252	Informative references	H10W 20/491
H10B 20/20	H01L 23/5256	Informative references	H10W 20/493
H10B 80/00	H01L 25/00	Informative references	H10W 90/00
H10B 80/00	H01L 25/00	Relationships with other classification places	H10W 90/00
H10B 80/00	H01L 25/00 and H01L 2225/00	Relationships with other classification places	H10W 90/00
H10D	H01L 23/00	Limiting references	H10W 99/00
H10D 89/60	H01L 23/60, H01L23/62	Informative references	H10W 42/60, H10W 42/80
H10F 39/80	H01L 23/28	Informative references	H10W 74/00

CPC NOTICE OF CHANGES 1859

DATE: JANUARY 1, 2026

PROJECT RP12819

<u>Location of reference to be changed</u>	<u>Referenced subclass or group to be changed</u>	<u>Section of definition</u>	<u>Action; New reference symbol; New text</u>
H10F 39/804	H01L 23/02	Informative references	H10W 76/10
H10F 39/804	H01L 23/28	Informative references	H10W 74/00
H10F 77/50	H01L 23/02	Informative references	H10W 76/10
H10F 77/50	H01L 23/28	Informative references	H10W 74/00
H10F 77/60	H01L 23/34	Informative references	H10W 40/00
H10F 77/63	H01L 23/38	Informative references	H10W 40/28
H10H 20/857	H01L 23/48, H01L23/52	Informative references	H10W 72/00
H10H 20/857	H01L 23/495	Informative references	H10W 70/40
H10H 20/858	H01L 23/34	Informative references	H10W 40/00
H10N 10/00	H01L 23/38	Informative references	H10W 40/28
H10N 19/00	H01L 23/38	Informative references	H10W 40/28

NOTES:

- The CRL tables above are used for changes to locations outside of the project scope. Changes to references in scheme titles or definitions inside the project scope will be reflected in the “scheme change” template or one of the “definition” templates.
- In addition to other changes proposed in the tables above, in the column titled “Referenced subclass or group to be changed,” referenced D symbols should indicate an action of “delete” or should indicate a replacement symbol and referenced F symbols should indicate a replacement symbol.
- When a reference is deleted, text related to that reference will also be deleted unless other references or a range of references associated with the same text remain.